

**POLITECNICO DI TORINO**  
**ESAMI DI STATO PER L'ABILITAZIONE ALL'ESERCIZIO**  
**DELLA PROFESSIONE DI INGEGNERE DELL'INFORMAZIONE**

**I Sessione 2019 - Sezione A**  
**Settore dell'Informazione**

**Prova PRATICA del 23 luglio 2019**

*Il Candidato svolga uno a scelta fra i seguenti temi proposti.*

*Gli elaborati prodotti dovranno essere stilati in forma chiara, ordinata, sintetica e leggibile.*

*La completezza, l'attinenza e la chiarezza espositiva costituiranno elementi di valutazione.*

**Tema n. 1**

Il candidato progetti un sistema per il controllo e la regolazione di un motore elettrico a corrente continua.

Il motore è un L149.12.43 della Micromotors, caratterizzato da un'alimentazione nominale di 12 V, velocità nominale di 60 RPM, rapporto di riduzione di 43,3:1 e momento di inerzia  $J=1.1 \cdot 10^{-5} \text{kg} \cdot \text{m}^2$  (datasheet in allegato). Inoltre, il motore include un sensore a effetto Hall e i relativi circuiti di condizionamento, che permettono di generare in uscita tre impulsi per rotazione (datasheet in allegato). Dalle misure effettuate, l'induttanza e la resistenza del motore sono  $R = 89 \Omega$  e  $L = 79 \text{mH}$ .

Si richiede il progetto del circuito di controllo della velocità del motore tramite la tecnica della modulazione a larghezza di impulso (PWM). In particolare, si faccia riferimento all'ipotesi in cui il motore non sia collegato ad alcun carico meccanico.

Per fornire i necessari livelli di tensione da applicare al motore, si può usare un driver opportuno, come per esempio l'L293 della Texas Instruments (datasheet in allegato).

Il sistema deve operare in due diverse modalità di funzionamento:

1. A anello aperto, con velocità minima pari a zero e massima pari a 4 rad/s. La velocità istantanea a vuoto deve essere proporzionale al valore binario su otto bit, letto da una porta di ingresso.
2. A anello chiuso in retroazione. In questo caso, il sistema legge l'effettiva velocità di rotazione del motore tramite il sensore a effetto Hall, misura la differenza rispetto alla velocità impostata sulla porta di ingresso e usa un controllo integrativo per regolare il motore.

La modalità di funzionamento e la direzione di rotazione sono imposte mediante due pulsanti esterni.

Per la realizzazione della parte digitale del sistema, il candidato ha a disposizione due opzioni:

1. Un microcontrollore, come l'STM32F4 (manuale allegato)
2. Un dispositivo FPGA, come il Cyclone V (datasheet allegato)

*Segue Tema 1 >>>*

È richiesto al candidato di:

- scegliere una delle due opzioni,
- progettare il circuito di alimentazione del controllore digitale (microcontrollore/FPGA), del driver e del sensore a effetto Hall a partire dalla rete elettrica 230V, 50Hz,
- progettare l'elettronica di interfaccia tra il microcontrollore (o la FPGA) e il motore nelle due modalità di funzionamento, dimensionando i componenti passivi necessari e dettagliando le specifiche di eventuali altre unità,
- progettare l'interfaccia tra il sensore ad effetto Hall e il microcontrollore/FPGA,
- fornire uno schema a blocchi dettagliato dell'intero sistema,
- derivare le equazioni per la regolazione della velocità del motore in PWM.

Il candidato, inoltre, completi il progetto sulla base della scelta effettuata: nel primo caso, fornisca il codice C per la configurazione del microcontrollore, la gestione delle periferiche utilizzate (in polling o in interrupt) e l'esecuzione dell'intera applicazione. Nel secondo caso, fornisca invece la vista a livello RTL (Register Transfer Level) dell'architettura digitale da sintetizzare sulla FPGA e il codice VHDL per i principali componenti allocati. Si privilegino scelte di progetto che minimizzino i costi produttivi e massimizzino l'efficienza energetica. Per le scelte di progetto lasciate libere e i dati non esplicitamente riportati nel testo si ricorra a ragionevoli e giustificate ipotesi.

Materiale in consultazione:

- All. 1: Datasheet del motore (L149.12.43, della Micromotors)
- All. 2: Datasheet del sensore ad effetto Hall
- All. 3: Datasheet del driver L293
- All. 4: Datasheet del microcontrollore STM32F401
- All. 5: Reference manual del microcontrollore STM32F4 (RM0368)
- All. 6: Datasheet del dispositivo Cyclone V

# DATI TECNICI TECHNICAL DATA

serie  
series

## L149



Soppressione disturbi con VDR sul collettore  
Spazzole in metallo prezioso (Au - Ag - Cu)  
Direzione di rotazione secondo polarità  
Può essere montato in ogni posizione  
Massimo carico radiale: 10N  
Massimo carico assiale: 5N  
Temperatura di esercizio: -20°C/60°C  
Peso approssimativo: 55g

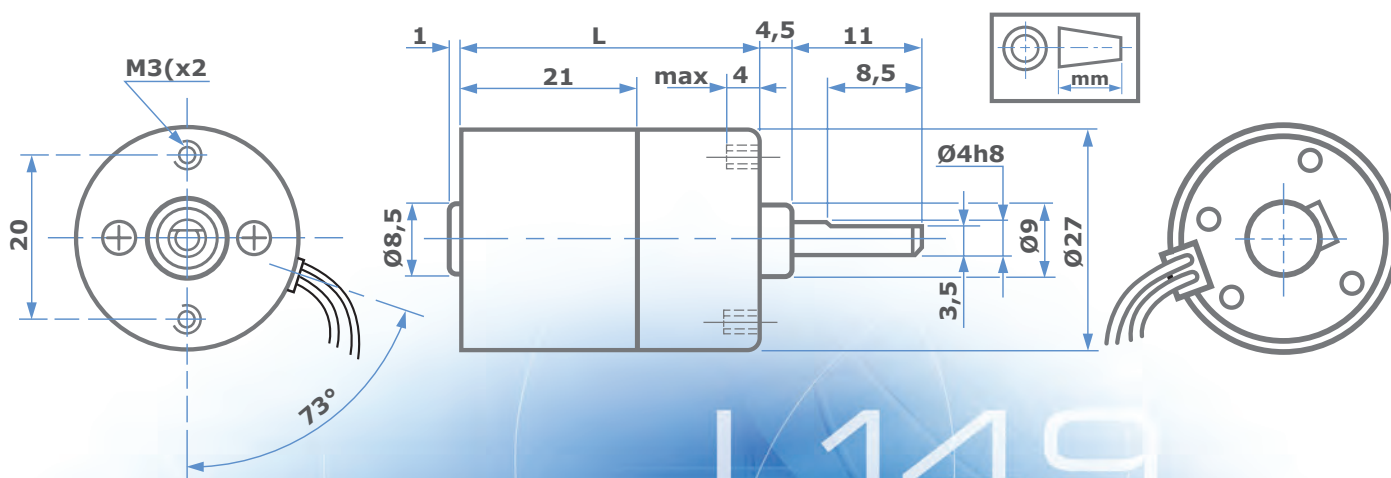
VDR interference suppression on the collector  
Precious metal brushes (Au - Ag - Cu)  
Direction of rotation depending on polarity  
Can be mounted in any position  
Maximum radial shaft load: 10N  
Maximum axial shaft load: 5N  
Temperature range: -20°C/60°C  
Approx weight: 55g

Valori tipici a temperatura ambiente +20°  
Tolleranza +/- 10%

Typical values at ambient temperature +20°  
Tolerance +/- 10%

TIPO TYPE	TENSIONE NOMINALE NOMINAL VOLTAGE	L	RAPPORTO :1 RATIO TO:1	COPPIA NOMINALE NOMINAL TORQUE	VELOCITÀ SPEED		CORRENTE CURRENT	
					SENZA CARICO NO LOAD	CON COPPIA NOMINALE AT NOMINAL TORQUE	SENZA CARICO NO LOAD	CON COPPIA NOMINALE AT NOMINAL TORQUE
	v	mm	Ncm	rpm	mA			
L149-6-10 12	4,5	36	10	1,5	255	165	<35	100
	6				215	120	<30	85
	12				255	165	<20	50
L149-6-21 12	4,5	36	20,8	2,5	125	80	<35	100
	6				105	60	<30	85
	12				125	80	<20	50
L149-6-43 12	4,5	41	43,3	3,8	60	40	<35	100
	6				52	32	<30	85
	12				60	40	<20	50
L149-6-90 12	4,5	41	90,3	8	30	18	<35	100
	6				25	13	<30	85
	12				30	18	<20	50
L149-6-188 12	4,5	46	188	14	14	9	<35	100
	6				12	7	<30	85
	12				14	9	<20	50
L149-6-392 12	4,5	46	391,8	20	7	5	<35	90
	6				6	4	<30	75
	12				7	5	<20	45

L149



# L149



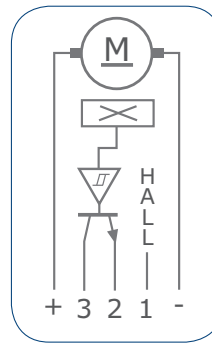
Viale Piave, 80/82 - 23879 VERDERIO (LC) ITALY  
Tel. 039.510611-499 Fax 039.513617  
www.micromotors.eu - info@micromotors.eu

## gear-motors with Hall-effect encoder

SIX POLES MAGNET:  
THREE PULSES FOR MOTOR TURN

### HALL-EFFECT SWITCHES

Hall-effect switches are highly temperature stable and stress-resistant sensors best utilized in applications that provide steep magnetic slopes and low residual levels of magnetic flux density. Each device includes a voltage regulator, quadratic Hall voltage generator, temperature stability circuit, signal chopper stabilized amplifier, Schmitt trigger and an open drain mosfet on a single silicon chip. The on-board regulator permits operation with supply voltages of 3.5 to 24V. The output mosfet can sink up to 20 mA with suitable output pull up. they can be used directly with bipolar or MOS logic circuits.



connections	
+ Red	: +Motor
3 Blue	: O.C. Output
2 Green	: Ground
1 Brown	: Vcc (Hall)
- Black	: -Motor



ABSOLUTE MAXIMUM RATINGS			
PARAMETER	SYMBOL	VALUE	UNITS
Supply Voltage	VDD	28	V
Supply Current	IDD	50	mA
Output Voltage	VOUT	28	V
Output Current	IOUT	50	mA
Storage Temperature Range	TS	-50 to 150	°C
Maximum Junction Temperature	TJ	2.0	°C

Exceeding the absolute maximum ratings may cause permanent damage. Exposure to all absolute-maximum-rated conditions for extended periods may affect device reliability.



GENERAL ELECTRICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYPE	MAX	UNITS
Supply Voltage	VDD	Operating	3.5	-	24	V
Supply Current	IDD	B<BRP	-	-	5	mA
Output Saturation Voltage	VDSon	IOUT=20mA. B>BOP	-	-	0.5	V
Output Leakage Current	IOFF	IB<BRP. VOUT=24V	-	0.3	10	µA
Output Rise Time	tr	RL=1kΩ. CL=20pF	-	0.25	-	µs
Output Fall Time	tr	RL=1kΩ. CL=20pF	-	0.25	-	µs

OC Operating Parameters TA = 25 °C, VDD = 3.5V to 24V (unless otherwise specified)

## L293x Quadruple Half-H Drivers

### 1 Features

- Wide Supply-Voltage Range: 4.5 V to 36 V
- Separate Input-Logic Supply
- Internal ESD Protection
- High-Noise-Immunity Inputs
- Output Current 1 A Per Channel (600 mA for L293D)
- Peak Output Current 2 A Per Channel (1.2 A for L293D)
- Output Clamp Diodes for Inductive Transient Suppression (L293D)

### 2 Applications

- Stepper Motor Drivers
- DC Motor Drivers
- Latching Relay Drivers

### 3 Description

The L293 and L293D devices are quadruple high-current half-H drivers. The L293 is designed to provide bidirectional drive currents of up to 1 A at voltages from 4.5 V to 36 V. The L293D is designed to provide bidirectional drive currents of up to 600-mA at voltages from 4.5 V to 36 V. Both devices are designed to drive inductive loads such as relays, solenoids, DC and bipolar stepping motors, as well as other high-current/high-voltage loads in positive-supply applications.

Each output is a complete totem-pole drive circuit, with a Darlington transistor sink and a pseudo-Darlington source. Drivers are enabled in pairs, with drivers 1 and 2 enabled by 1,2EN and drivers 3 and 4 enabled by 3,4EN.

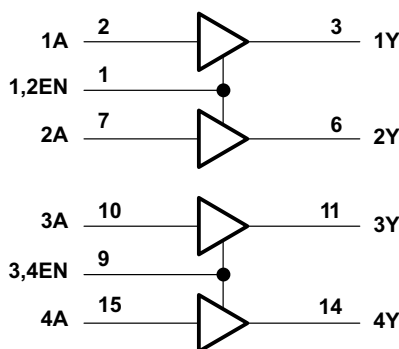
The L293 and L293D are characterized for operation from 0°C to 70°C.

#### Device Information<sup>(1)</sup>

PART NUMBER	PACKAGE	BODY SIZE (NOM)
L293NE	PDIP (16)	19.80 mm x 6.35 mm
L293DNE	PDIP (16)	19.80 mm x 6.35 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

#### Logic Diagram



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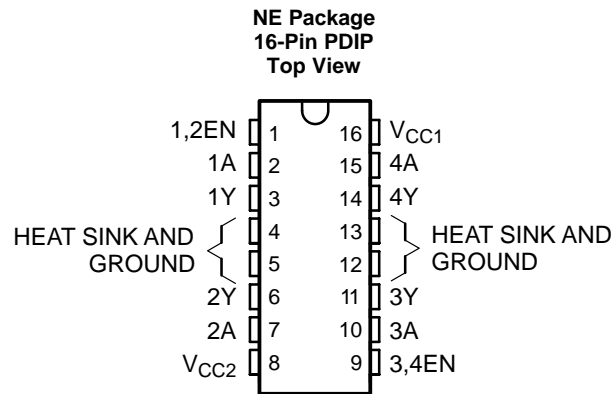
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## 4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

<b>Changes from Revision C (November 2004) to Revision D</b>	<b>Page</b>
• Removed <i>Ordering Information</i> table .....	<b>1</b>
• Added <i>ESD Ratings</i> and <i>Thermal Information</i> tables, <i>Feature Description</i> section, <i>Device Functional Modes</i> , <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section. ....	<b>1</b>

## 5 Pin Configuration and Functions



### Pin Functions

PIN		TYPE	DESCRIPTION
NAME	NO.		
1,2EN	1	I	Enable driver channels 1 and 2 (active high input)
<1:4>A	2, 7, 10, 15	I	Driver inputs, noninverting
<1:4>Y	3, 6, 11, 14	O	Driver outputs
3,4EN	9	I	Enable driver channels 3 and 4 (active high input)
GROUND	4, 5, 12, 13	—	Device ground and heat sink pin. Connect to printed-circuit-board ground plane with multiple solid vias
V <sub>CC1</sub>	16	—	5-V supply for internal logic translation
V <sub>CC2</sub>	8	—	Power VCC for drivers 4.5 V to 36 V

## 6 Specifications

### 6.1 Absolute Maximum Ratings

 over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

	MIN	MAX	UNIT
Supply voltage, $V_{CC1}$ <sup>(2)</sup>		36	V
Output supply voltage, $V_{CC2}$		36	V
Input voltage, $V_I$		7	V
Output voltage, $V_O$	-3	$V_{CC2} + 3$	V
Peak output current, $I_O$ (nonrepetitive, $t \leq 5$ ms): L293	-2	2	A
Peak output current, $I_O$ (nonrepetitive, $t \leq 100$ $\mu$ s): L293D	-1.2	1.2	A
Continuous output current, $I_O$ : L293	-1	1	A
Continuous output current, $I_O$ : L293D	-600	600	mA
Maximum junction temperature, $T_J$		150	°C
Storage temperature, $T_{stg}$	-65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values are with respect to the network ground terminal.

### 6.2 ESD Ratings

		VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	$\pm 2000$
		Charged-device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup>	$\pm 1000$
			V

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
Supply voltage	$V_{CC1}$	4.5		7	V
	$V_{CC2}$	$V_{CC1}$		36	
$V_{IH}$	High-level input voltage	$V_{CC1} \leq 7$ V		$V_{CC1}$	V
		$V_{CC1} \geq 7$ V	2.3	7	V
$V_{IL}$	Low-level output voltage	-0.3 <sup>(1)</sup>		1.5	V
$T_A$	Operating free-air temperature	0		70	°C

- (1) The algebraic convention, in which the least positive (most negative) designated minimum, is used in this data sheet for logic voltage levels.

### 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		L293, L293D	UNIT
		NE (PDIP)	
		16 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance <sup>(2)</sup>	36.4	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	22.5	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	16.5	°C/W
$\Psi_{JT}$	Junction-to-top characterization parameter	7.1	°C/W
$\Psi_{JB}$	Junction-to-board characterization parameter	16.3	°C/W

- (1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).
- (2) The package thermal impedance is calculated in accordance with JESD 51-7.



### 6.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
V <sub>OH</sub>	High-level output voltage	L293: I <sub>OH</sub> = -1 A		V <sub>CC2</sub> - 1.8	V <sub>CC2</sub> - 1.4		V
		L293D: I <sub>OH</sub> = -0.6 A					
V <sub>OL</sub>	Low-level output voltage	L293: I <sub>OL</sub> = 1 A			1.2	1.8	V
		L293D: I <sub>OL</sub> = 0.6 A					
V <sub>OKH</sub>	High-level output clamp voltage	L293D: I <sub>OK</sub> = -0.6 A		V <sub>CC2</sub> + 1.3			V
V <sub>OKL</sub>	Low-level output clamp voltage	L293D: I <sub>OK</sub> = 0.6 A		1.3			V
I <sub>IH</sub>	High-level input current	A	V <sub>I</sub> = 7 V	0.2		100	μA
		EN		0.2		10	
I <sub>IL</sub>	Low-level input current	A	V <sub>I</sub> = 0	-3		-10	μA
		EN		-2		-100	
I <sub>CC1</sub>	Logic supply current	I <sub>O</sub> = 0	All outputs at high level	13		22	mA
			All outputs at low level	35		60	
			All outputs at high impedance	8		24	
I <sub>CC2</sub>	Output supply current	I <sub>O</sub> = 0	All outputs at high level	14		24	mA
			All outputs at low level	2		6	
			All outputs at high impedance	2		4	

### 6.6 Switching Characteristics

over operating free-air temperature range (unless otherwise noted) V<sub>CC1</sub> = 5 V, V<sub>CC2</sub> = 24 V, T<sub>A</sub> = 25°C

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
t <sub>PLH</sub>	Propagation delay time, low-to-high-level output from A input	L293NE, L293DNE		800			ns
		L293DWP, L293N L293DN		750			
t <sub>PHL</sub>	Propagation delay time, high-to-low-level output from A input	L293NE, L293DNE		400			ns
		L293DWP, L293N L293DN		200			
t <sub>TLH</sub>	Transition time, low-to-high-level output	L293NE, L293DNE		300			ns
		L293DWP, L293N L293DN		100			
t <sub>THL</sub>	Transition time, high-to-low-level output	L293NE, L293DNE		300			ns
		L293DWP, L293N L293DN		350			

C<sub>L</sub> = 30 pF, See Figure 2

### 6.7 Typical Characteristics

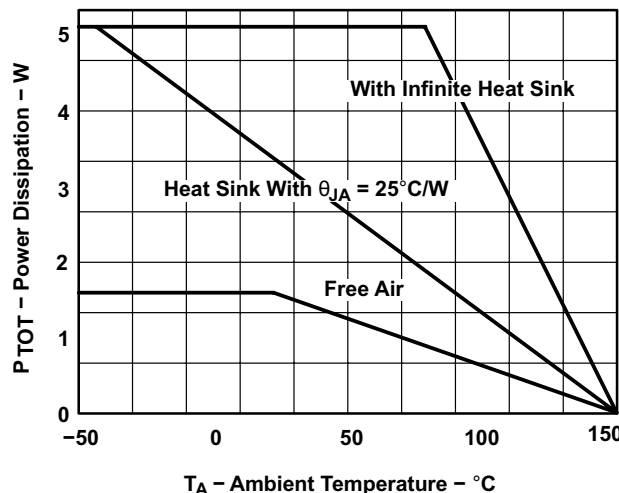
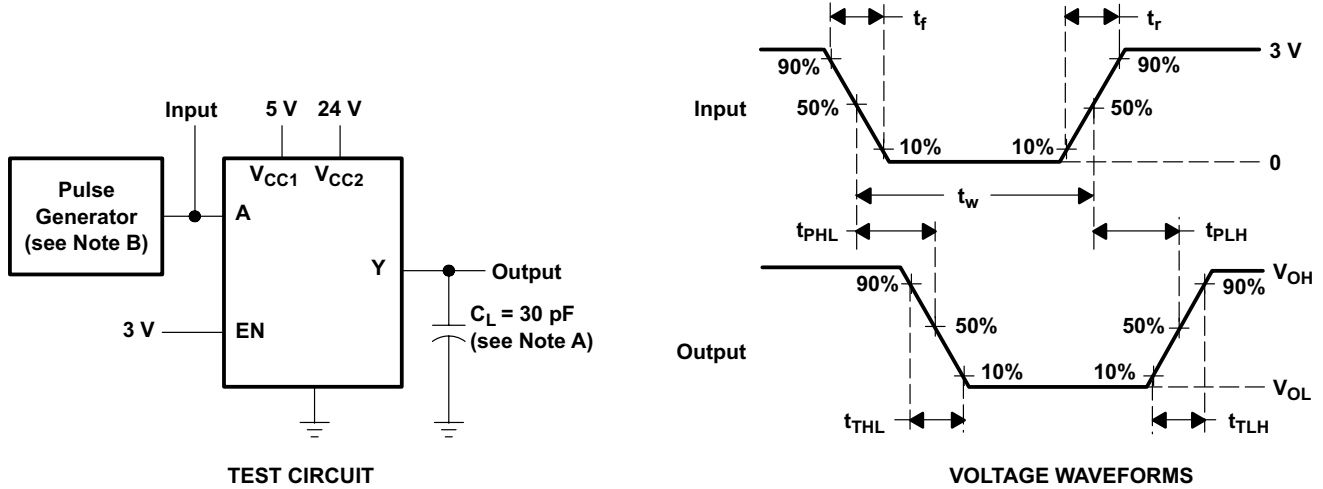


Figure 1. Maximum Power Dissipation vs Ambient Temperature

## 7 Parameter Measurement Information



NOTES: A.  $C_L$  includes probe and jig capacitance.

B. The pulse generator has the following characteristics:  $t_r \leq 10$  ns,  $t_f \leq 10$  ns,  $t_w = 10$   $\mu$ s, PRR = 5 kHz,  $Z_O = 50$   $\Omega$ .

**Figure 2. Test Circuit and Voltage Waveforms**

## 8 Detailed Description

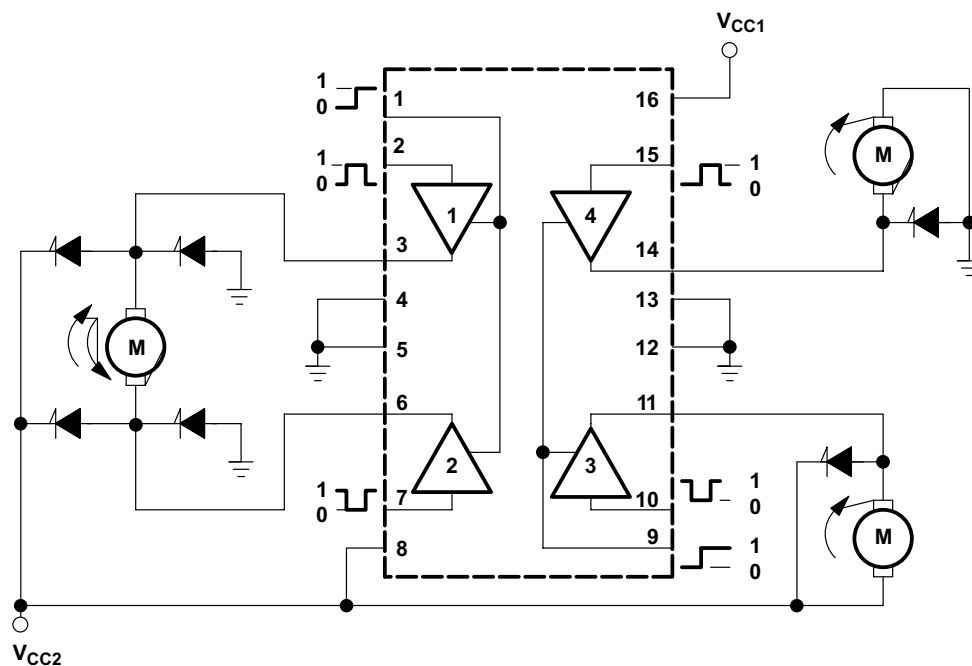
### 8.1 Overview

The L293 and L293D are quadruple high-current half-H drivers. These devices are designed to drive a wide array of inductive loads such as relays, solenoids, DC and bipolar stepping motors, as well as other high-current and high-voltage loads. All inputs are TTL compatible and tolerant up to 7 V.

Each output is a complete totem-pole drive circuit, with a Darlington transistor sink and a pseudo-Darlington source. Drivers are enabled in pairs, with drivers 1 and 2 enabled by 1,2EN and drivers 3 and 4 enabled by 3,4EN. When an enable input is high, the associated drivers are enabled, and their outputs are active and in phase with their inputs. When the enable input is low, those drivers are disabled, and their outputs are off and in the high-impedance state. With the proper data inputs, each pair of drivers forms a full-H (or bridge) reversible drive suitable for solenoid or motor applications.

On the L293, external high-speed output clamp diodes should be used for inductive transient suppression. On the L293D, these diodes are integrated to reduce system complexity and overall system size. A  $V_{CC1}$  terminal, separate from  $V_{CC2}$ , is provided for the logic inputs to minimize device power dissipation. The L293 and L293D are characterized for operation from 0°C to 70°C.

### 8.2 Functional Block Diagram



Output diodes are internal in L293D.

### 8.3 Feature Description

The L293x has TTL-compatible inputs and high voltage outputs for inductive load driving. Current outputs can get up to 2 A using the L293.

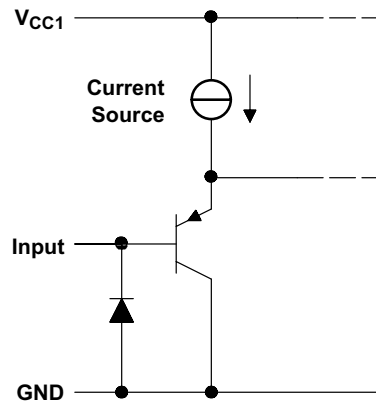
### 8.4 Device Functional Modes

Table 1 lists the functional modes of the L293x.

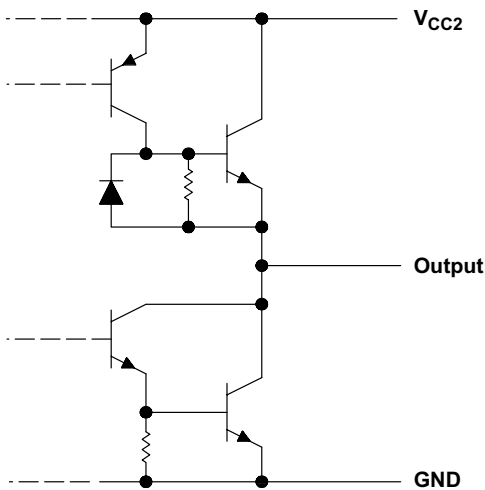
**Table 1. Function Table (Each Driver)<sup>(1)</sup>**

INPUTS <sup>(2)</sup>		OUTPUT (Y)
A	EN	
H	H	H
L	H	L
X	L	Z

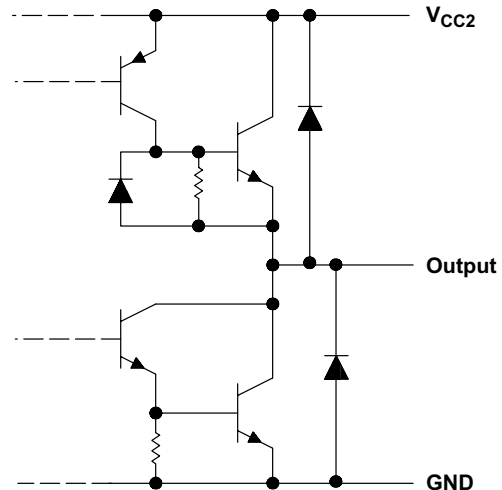
- (1) H = high level, L = low level, X = irrelevant, Z = high impedance (off)
- (2) In the thermal shutdown mode, the output is in the high-impedance state, regardless of the input levels.



**Figure 3. Schematic of Inputs for the L293x**



**Figure 4. Schematic of Outputs for the L293**



**Figure 5. Schematic of Outputs for the L293D**

## 9 Application and Implementation

### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 9.1 Application Information

A typical application for the L293 device is driving a two-phase motor. Below is an example schematic displaying how to properly connect a two-phase motor to the L293 device.

Provide a 5-V supply to  $V_{CC1}$  and valid logic input levels to data and enable inputs.  $V_{CC2}$  must be connected to a power supply capable of supplying the needed current and voltage demand for the loads connected to the outputs.

### 9.2 Typical Application

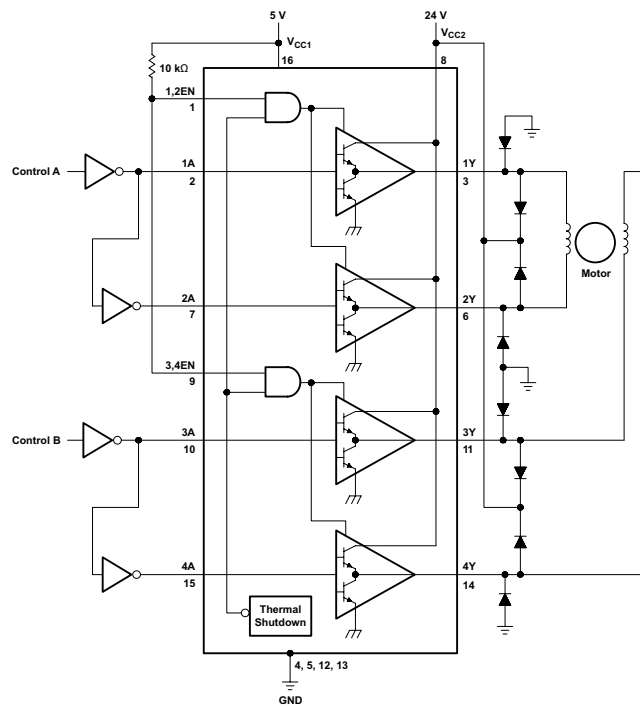


Figure 6. Two-Phase Motor Driver (L293)

#### 9.2.1 Design Requirements

The design techniques in the application above as well as the applications below should fall within the following design requirements.

1.  $V_{CC1}$  should fall within the limits described in the [Recommended Operating Conditions](#).
2.  $V_{CC2}$  should fall within the limits described in the [Recommended Operating Conditions](#).
3. The current per channel should not exceed 1 A for the L293 (600mA for the L293D).

#### 9.2.2 Detailed Design Procedure

When designing with the L293 or L293D, careful consideration should be made to ensure the device does not exceed the operating temperature of the device. Proper heatsinking will allow for operation over a larger range of current per channel. Refer to the [Power Supply Recommendations](#) as well as the [Layout Example](#).

## Typical Application (continued)

### 9.2.3 Application Curve

Refer to [Power Supply Recommendations](#) for additional information with regards to appropriate power dissipation. Figure 7 describes thermal dissipation based on Figure 14.

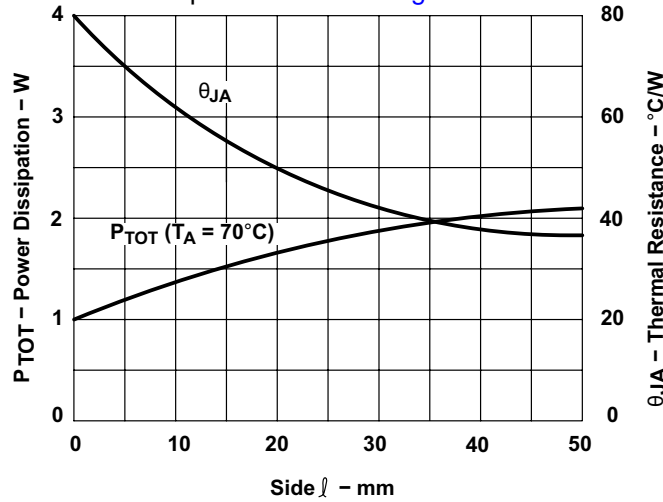


Figure 7. Maximum Power and Junction vs Thermal Resistance

## 9.3 System Examples

### 9.3.1 L293D as a Two-Phase Motor Driver

Figure 8 below depicts a typical setup for using the L293D as a two-phase motor driver. Refer to the [Recommended Operating Conditions](#) when considering the appropriate input high and input low voltage levels to enable each channel of the device.

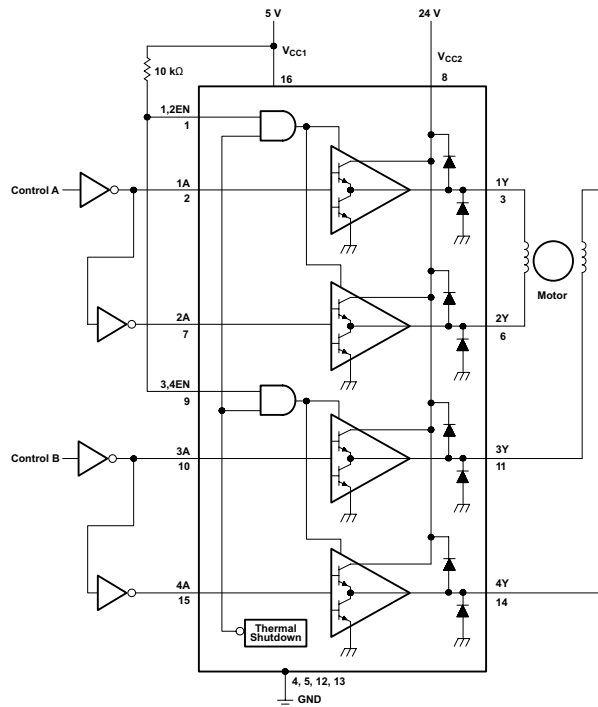
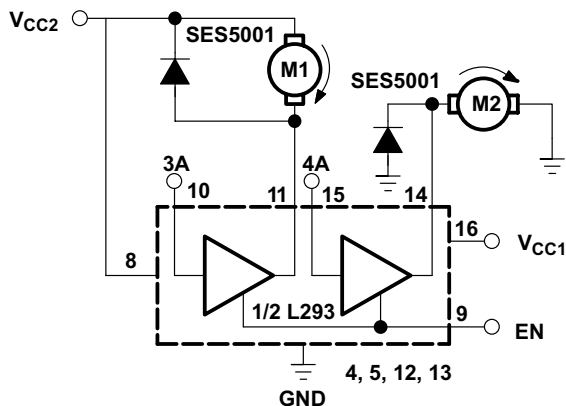


Figure 8. Two-Phase Motor Driver (L293D)

### System Examples (continued)

#### 9.3.2 DC Motor Controls

Figure 9 and Figure 10 below depict a typical setup for using the L293 device as a controller for DC motors. Note that the L293 device can be used as a simple driver for a motor to turn on and off in one direction, and can also be used to drive a motor in both directions. Refer to the function tables below to understand unidirectional vs bidirectional motor control. Refer to the *Recommended Operating Conditions* when considering the appropriate input high and input low voltage levels to enable each channel of the device.



Connections to ground and to supply voltage

Figure 9. DC Motor Controls

Table 2. Unidirectional DC Motor Control

EN	3A	M1 <sup>(1)</sup>	4A	M2
H	H	Fast motor stop	H	Run
H	L	run	L	Fast motor stop
L	X	Free-running motor stop	X	Free-running motor stop

(1) L = low, H = high, X = don't care

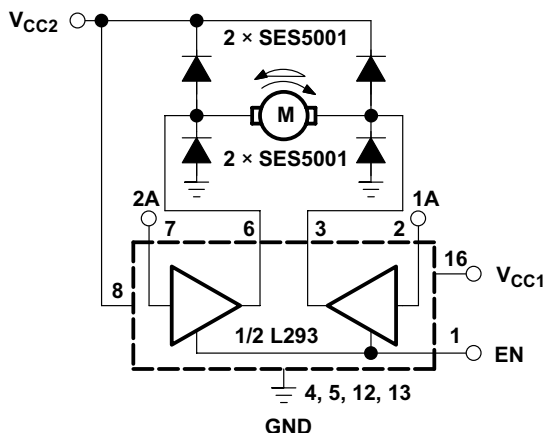


Figure 10. Bidirectional DC Motor Control

Table 3. Bidirectional DC Motor Control

EN	1A	2A	FUNCTION <sup>(1)</sup>
H	L	H	Turn right
H	H	L	Turn left

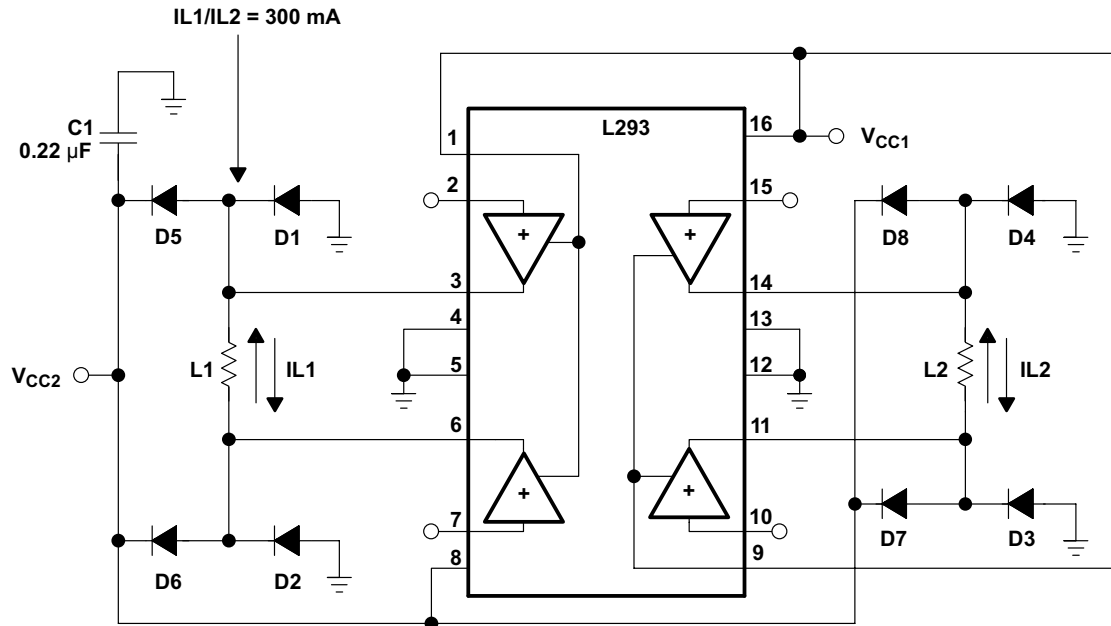
(1) L = low, H = high, X = don't care

**Table 3. Bidirectional DC Motor Control (continued)**

EN	1A	2A	FUNCTION <sup>(1)</sup>
H	L	L	Fast motor stop
H	H	H	Fast motor stop
L	X	X	Free-running motor stop

### 9.3.3 Bipolar Stepping-Motor Control

Figure 11 below depicts a typical setup for using the L293D as a two-phase motor driver. Refer to the [Recommended Operating Conditions](#) when considering the appropriate input high and input low voltage levels to enable each channel of the device.



D1–D8 = SES5001

**Figure 11. Bipolar Stepping-Motor Control**



## 10 Power Supply Recommendations

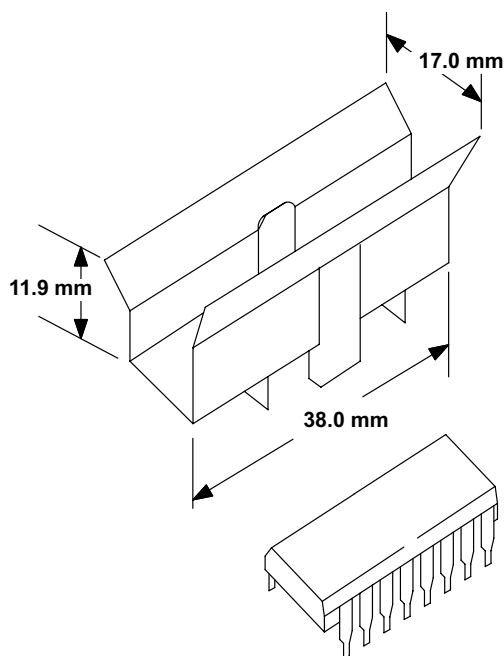
$V_{CC1}$  is  $5\text{ V} \pm 0.5\text{ V}$  and  $V_{CC2}$  can be same supply as  $V_{CC1}$  or a higher voltage supply with peak voltage up to 36 V. Bypass capacitors of 0.1  $\mu\text{F}$  or greater should be used at  $V_{CC1}$  and  $V_{CC2}$  pins. There are no power up or power down supply sequence order requirements.

Properly heatsinking the L293 when driving high-current is critical to design. The  $R_{thj-amp}$  of the L293 can be reduced by soldering the GND pins to a suitable copper area of the printed circuit board or to an external heat sink.

Figure 14 shows the maximum package power  $PTOT$  and the  $\theta_{JA}$  as a function of the side of two equal square copper areas having a thickness of 35  $\mu\text{m}$  (see Figure 14). In addition, an external heat sink can be used (see Figure 12).

During soldering, the pin temperature must not exceed 260°C, and the soldering time must not exceed 12 seconds.

The external heatsink or printed circuit copper area must be connected to electrical ground.



**Figure 12. External Heat Sink Mounting Example ( $\theta_{JA} = 25^\circ\text{C/W}$ )**

## 11 Layout

### 11.1 Layout Guidelines

Place the device near the load to keep output traces short to reduce EMI. Use solid vias to transfer heat from ground pins to ground plane of the printed-circuit-board.

### 11.2 Layout Example

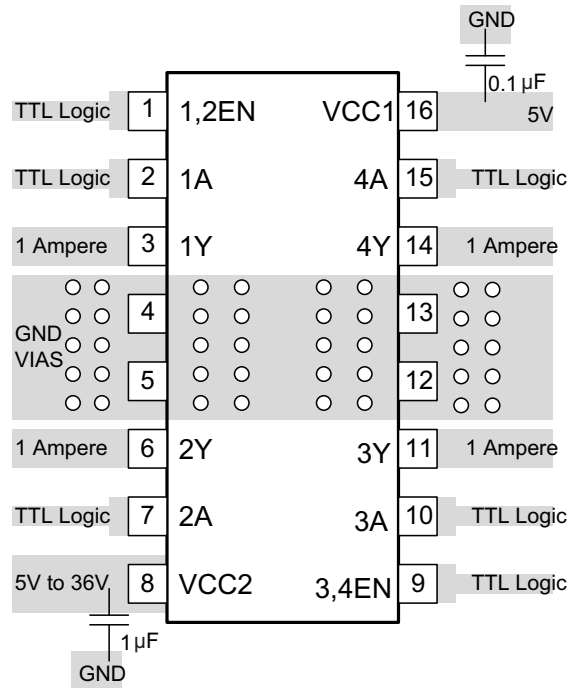


Figure 13. Layout Diagram

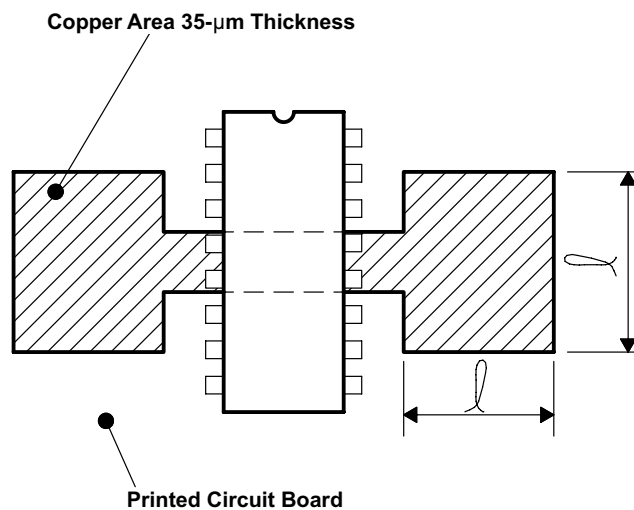


Figure 14. Example of Printed-Circuit-Board Copper Area (Used as Heat Sink)

## 12 Device and Documentation Support

### 12.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

**Table 4. Related Links**

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
L293	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>
L293D	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>

### 12.2 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

**TI E2E™ Online Community** *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At [e2e.ti.com](http://e2e.ti.com), you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

**Design Support** *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

### 12.3 Trademarks

E2E is a trademark of Texas Instruments.  
All other trademarks are the property of their respective owners.

### 12.4 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### 12.5 Glossary

**SLYZ022** — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
L293DNE	ACTIVE	PDIP	NE	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	L293DNE	<a href="#">Samples</a>
L293DNEE4	ACTIVE	PDIP	NE	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	L293DNE	<a href="#">Samples</a>
L293NE	ACTIVE	PDIP	NE	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	L293NE	<a href="#">Samples</a>
L293NEE4	ACTIVE	PDIP	NE	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	L293NE	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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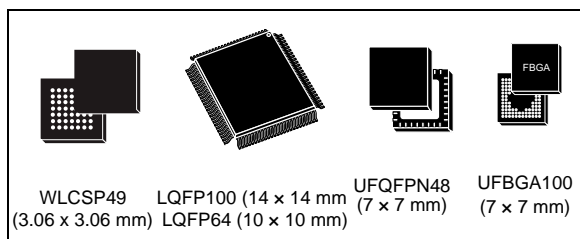
# STM32F401xD STM32F401xE

ARM<sup>®</sup> Cortex<sup>®</sup>-M4 32b MCU+FPU, 105 DMIPS,  
512KB Flash/96KB RAM, 11 TIMs, 1 ADC, 11 comm. interfaces

Datasheet - production data

## Features

- Core: ARM<sup>®</sup> 32-bit Cortex<sup>®</sup>-M4 CPU with FPU, Adaptive real-time accelerator (ART Accelerator<sup>™</sup>) allowing 0-wait state execution from Flash memory, frequency up to 84 MHz, memory protection unit, 105 DMIPS/1.25 DMIPS/MHz (Dhrystone 2.1), and DSP instructions
- Memories
  - up to 512 Kbytes of Flash memory
  - up to 96 Kbytes of SRAM
- Clock, reset and supply management
  - 1.7 V to 3.6 V application supply and I/Os
  - POR, PDR, PVD and BOR
  - 4-to-26 MHz crystal oscillator
  - Internal 16 MHz factory-trimmed RC
  - 32 kHz oscillator for RTC with calibration
  - Internal 32 kHz RC with calibration
- Power consumption
  - Run: 146  $\mu$ A/MHz (peripheral off)
  - Stop (Flash in Stop mode, fast wakeup time): 42  $\mu$ A Typ @ 25°C; 65  $\mu$ A max @25 °C
  - Stop (Flash in Deep power down mode, fast wakeup time): down to 10  $\mu$ A @ 25 °C; 30  $\mu$ A max @25 °C
  - Standby: 2.4  $\mu$ A @25 °C / 1.7 V without RTC; 12  $\mu$ A @85 °C @1.7 V
  - V<sub>BAT</sub> supply for RTC: 1  $\mu$ A @25 °C
- 1x12-bit, 2.4 MSPS A/D converter: up to 16 channels
- General-purpose DMA: 16-stream DMA controllers with FIFOs and burst support
- Up to 11 timers: up to six 16-bit, two 32-bit timers up to 84 MHz, each with up to four IC/OC/PWM or pulse counter and quadrature (incremental) encoder input, two watchdog timers (independent and window) and a SysTick timer



- Debug mode
  - Serial wire debug (SWD) & JTAG interfaces
  - Cortex<sup>®</sup>-M4 Embedded Trace Macrocell<sup>™</sup>
- Up to 81 I/O ports with interrupt capability
  - Up to 78 fast I/Os up to 42 MHz
  - All I/O ports are 5 V-tolerant
- Up to 12 communication interfaces
  - Up to 3 x I<sup>2</sup>C interfaces (SMBus/PMBus)
  - Up to 3 USARTs (2 x 10.5 Mbit/s, 1 x 5.25 Mbit/s), ISO 7816 interface, LIN, IrDA, modem control)
  - Up to 4 SPIs (up to 42Mbit/s at f<sub>CPU</sub> = 84 MHz), SPI2 and SPI3 with muxed full-duplex I<sup>2</sup>S to achieve audio class accuracy via internal audio PLL or external clock
  - SDIO interface
  - Advanced connectivity: USB 2.0 full-speed device/host/OTG controller with on-chip PHY
- CRC calculation unit
- 96-bit unique ID
- RTC: subsecond accuracy, hardware calendar
- All packages (WLCSP49, LQFP64/100, UFQFPN48, UFBGA100) are ECOPACK<sup>®</sup>2

Table 1. Device summary

Reference	Part number
STM32F401xD	STM32F401CD, STM32F401RD, STM32F401VD
STM32F401xE	STM32F401CE, STM32F401RE, STM32F401VE

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# 1 Introduction

This datasheet provides the description of the STM32F401xD/xE line of microcontrollers.

The STM32F401xD/xE datasheet should be read in conjunction with RM0368 reference manual which is available from the STMicroelectronics website [www.st.com](http://www.st.com). It includes all information concerning Flash memory programming.

For information on the Cortex<sup>®</sup>-M4 core, please refer to the Cortex<sup>®</sup>-M4 programming manual (PM0214) available from [www.st.com](http://www.st.com).



## 2 Description

The STM32F401xD/xE devices are based on the high-performance ARM® Cortex®-M4 32-bit RISC core operating at a frequency of up to 84 MHz. Its Cortex®-M4 core features a Floating point unit (FPU) single precision which supports all ARM single-precision data-processing instructions and data types. It also implements a full set of DSP instructions and a memory protection unit (MPU) which enhances application security.

The STM32F401xD/xE incorporate high-speed embedded memories (512 Kbytes of Flash memory, 96 Kbytes of SRAM), and an extensive range of enhanced I/Os and peripherals connected to two APB buses, two AHB buses and a 32-bit multi-AHB bus matrix.

All devices offer one 12-bit ADC, a low-power RTC, six general-purpose 16-bit timers including one PWM timer for motor control, two general-purpose 32-bit timers. They also feature standard and advanced communication interfaces.

- Up to three I<sup>2</sup>Cs
- Up to four SPIs
- Two full duplex I<sup>2</sup>Ss. To achieve audio class accuracy, the I<sup>2</sup>S peripherals can be clocked via a dedicated internal audio PLL or via an external clock to allow synchronization.
- Three USARTs
- SDIO interface
- USB 2.0 OTG full speed interface

Refer to [Table 1](#) for the peripherals available for each part number.

The STM32F401xD/xE operate in the –40 to +105 °C temperature range from a 1.7 (PDR OFF) to 3.6 V power supply. A comprehensive set of power-saving mode allows the design of low-power applications.

These features make the STM32F401xD/xE microcontrollers suitable for a wide range of applications:

- Motor drive and application control
- Medical equipment
- Industrial applications: PLC, inverters, circuit breakers
- Printers, and scanners
- Alarm systems, video intercom, and HVAC
- Home audio appliances
- Mobile phone sensor hub

[Figure 3](#) shows the general block diagram of the devices.



**Table 2. STM32F401xD/xE features and peripheral counts**

Peripherals		STM32F401xD			STM32F401xE		
Flash memory in Kbytes		384			512		
SRAM in Kbytes	System	96					
Timers	General-purpose	7					
	Advanced-control	1					
Communication interfaces	SPI/ I <sup>2</sup> S	3/2 (full duplex)		4/2 (full duplex)	3/2 (full duplex)		4/2 (full duplex)
	I <sup>2</sup> C	3					
	USART	3					
	SDIO	-	1		-	1	
USB OTG FS		1					
GPIOs		36	50	81	36	50	81
12-bit ADC		1					
Number of channels		10	16		10	16	
Maximum CPU frequency		84 MHz					
Operating voltage		1.7 to 3.6 V					
Operating temperatures		Ambient temperatures: -40 to +85 °C/-40 to +105 °C					
		Junction temperature: -40 to + 125 °C					
Package		WLCSP49 UFQFPN48	LQFP64	UFBGA100 LQFP100	WLCSP49 UFQFPN48	LQFP64	UFBGA100 LQFP100

## 2.1 Compatibility with STM32F4 series

The STM32F401xD/xE are fully software and feature compatible with the STM32F4 series (STM32F42x, STM32F43x, STM32F41x, STM32F405 and STM32F407)

The STM32F401xD/xE can be used as drop-in replacement of the other STM32F4 products but some slight changes have to be done on the PCB board.

Figure 1. Compatible board design for LQFP100 package

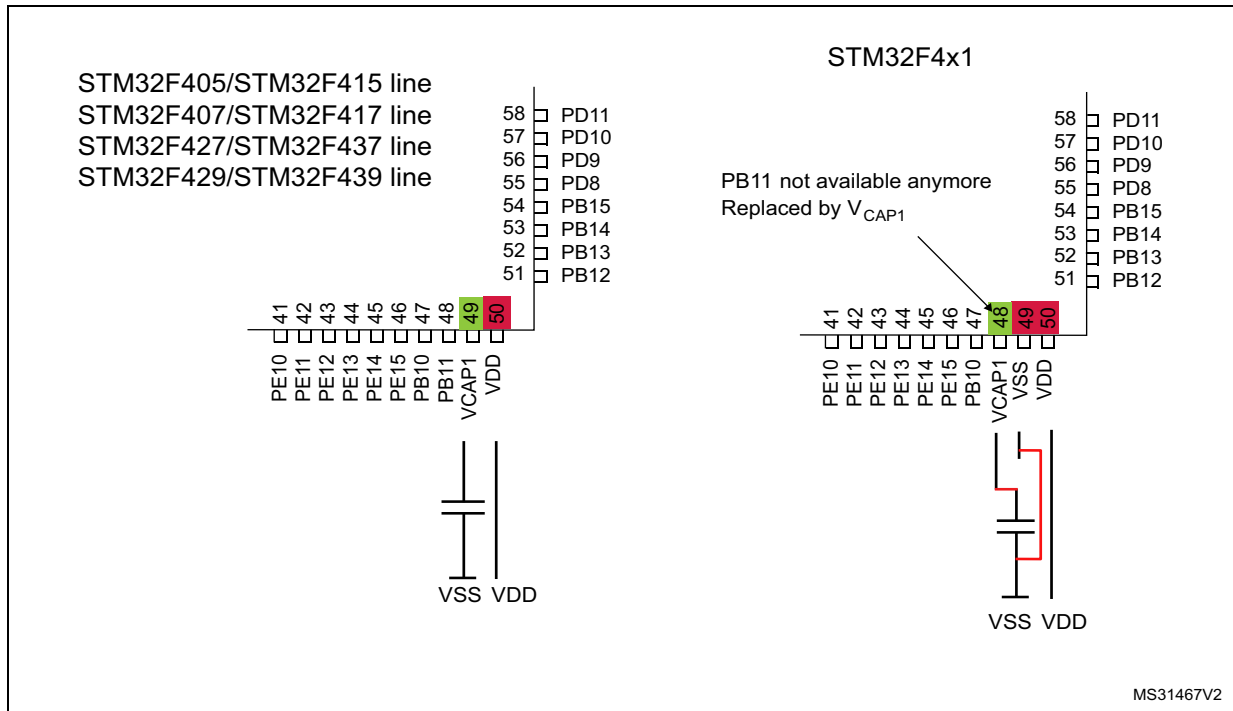


Figure 2. Compatible board design for LQFP64 package

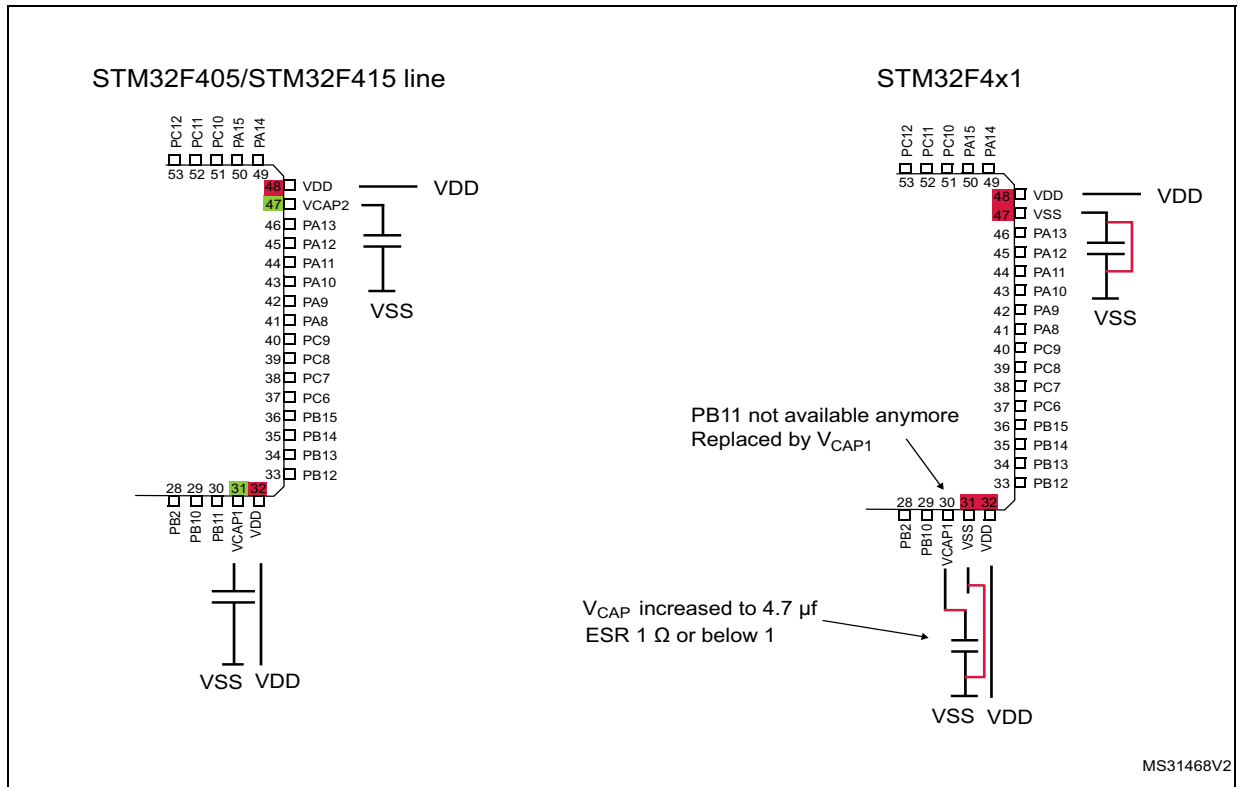
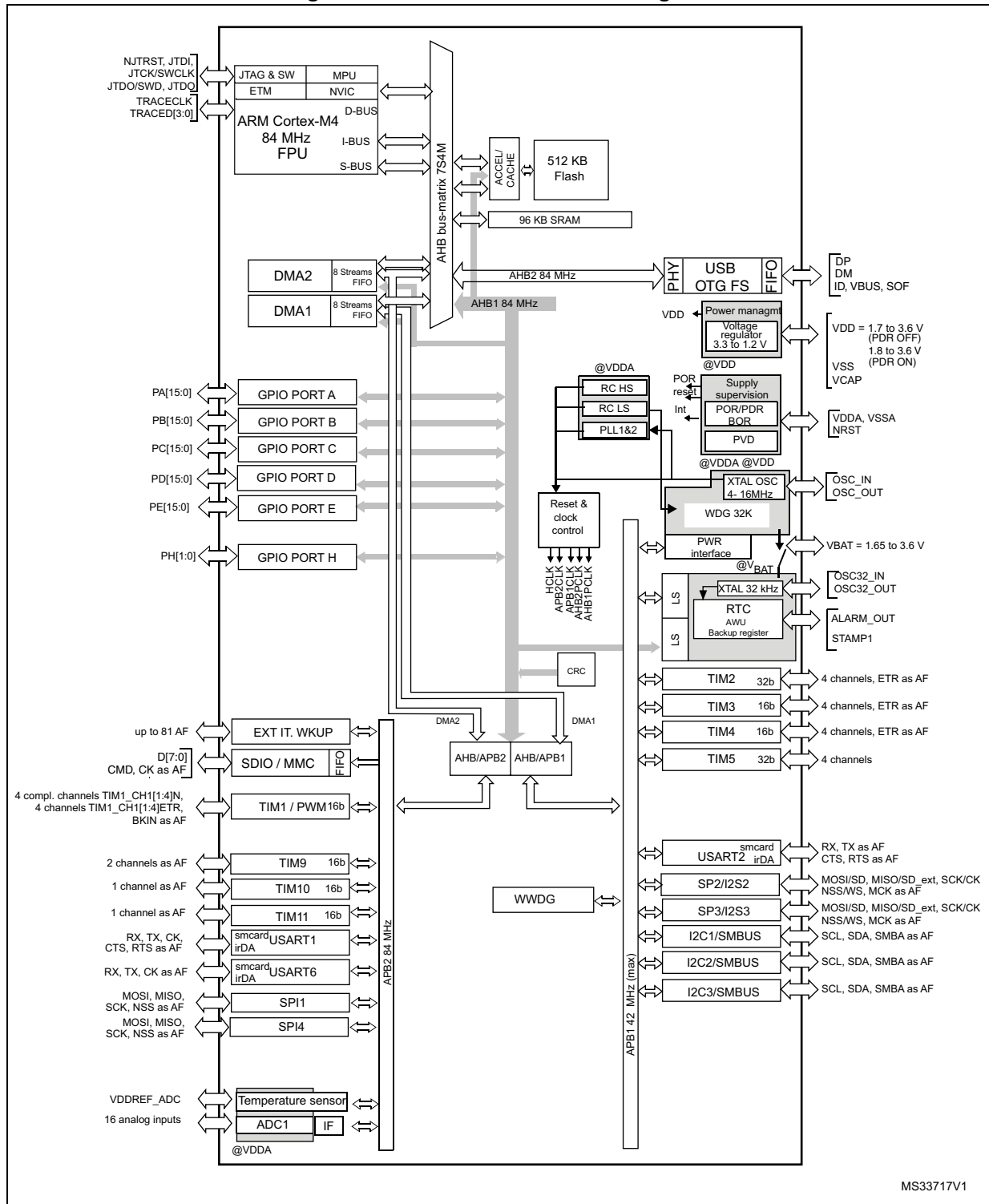


Figure 3. STM32F401xD/xE block diagram



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1. The timers connected to APB2 are clocked from TIMxCLK up to 84 MHz, while the timers connected to APB1 are clocked from TIMxCLK up to 42 MHz.

## 3 Functional overview

### 3.1 ARM<sup>®</sup> Cortex<sup>®</sup>-M4 with FPU core with embedded Flash and SRAM

The ARM<sup>®</sup> Cortex<sup>®</sup>-M4 with FPU processor is the latest generation of ARM processors for embedded systems. It was developed to provide a low-cost platform that meets the needs of MCU implementation, with a reduced pin count and low-power consumption, while delivering outstanding computational performance and an advanced response to interrupts.

The ARM<sup>®</sup> Cortex<sup>®</sup>-M4 with FPU 32-bit RISC processor features exceptional code-efficiency, delivering the high-performance expected from an ARM core in the memory size usually associated with 8- and 16-bit devices. The processor supports a set of DSP instructions which allow efficient signal processing and complex algorithm execution. Its single precision FPU (floating point unit) speeds up software development by using metalanguage development tools, while avoiding saturation.

The STM32F401xD/xE devices are compatible with all ARM tools and software.

*Figure 3* shows the general block diagram of the STM32F401xD/xE.

*Note:* Cortex<sup>®</sup>-M4 with FPU is binary compatible with Cortex<sup>®</sup>-M3.

### 3.2 Adaptive real-time memory accelerator (ART Accelerator<sup>™</sup>)

The ART Accelerator<sup>™</sup> is a memory accelerator which is optimized for STM32 industry-standard ARM<sup>®</sup> Cortex<sup>®</sup>-M4 with FPU processors. It balances the inherent performance advantage of the ARM<sup>®</sup> Cortex<sup>®</sup>-M4 with FPU over Flash memory technologies, which normally requires the processor to wait for the Flash memory at higher frequencies.

To release the processor full 105 DMIPS performance at this frequency, the accelerator implements an instruction prefetch queue and branch cache, which increases program execution speed from the 128-bit Flash memory. Based on CoreMark benchmark, the performance achieved thanks to the ART accelerator is equivalent to 0 wait state program execution from Flash memory at a CPU frequency up to 84 MHz.

### 3.3 Memory protection unit

The memory protection unit (MPU) is used to manage the CPU accesses to memory to prevent one task to accidentally corrupt the memory or resources used by any other active task. This memory area is organized into up to 8 protected areas that can in turn be divided up into 8 subareas. The protection area sizes are between 32 bytes and the whole 4 gigabytes of addressable memory.

The MPU is especially helpful for applications where some critical or certified code has to be protected against the misbehavior of other tasks. It is usually managed by an RTOS (real-time operating system). If a program accesses a memory location that is prohibited by the MPU, the RTOS can detect it and take action. In an RTOS environment, the kernel can dynamically update the MPU area setting, based on the process to be executed.

The MPU is optional and can be bypassed for applications that do not need it.

### 3.4 Embedded Flash memory

The devices embed 512 Kbytes of Flash memory available for storing programs and data.

### 3.5 CRC (cyclic redundancy check) calculation unit

The CRC (cyclic redundancy check) calculation unit is used to get a CRC code from a 32-bit data word and a fixed generator polynomial.

Among other applications, CRC-based techniques are used to verify data transmission or storage integrity. In the scope of the EN/IEC 60335-1 standard, they offer a means of verifying the Flash memory integrity. The CRC calculation unit helps compute a software signature during runtime, to be compared with a reference signature generated at link-time and stored at a given memory location.

### 3.6 Embedded SRAM

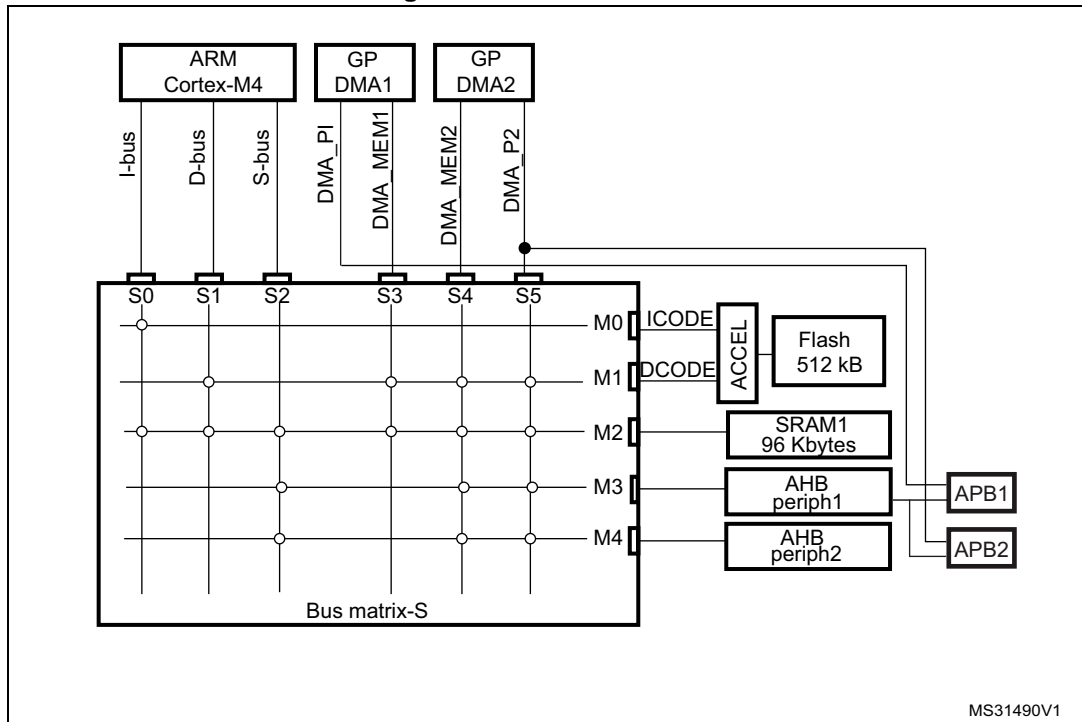
All devices embed:

- 96 Kbytes of system SRAM which can be accessed (read/write) at CPU clock speed with 0 wait states

### 3.7 Multi-AHB bus matrix

The 32-bit multi-AHB bus matrix interconnects all the masters (CPU, DMAs) and the slaves (Flash memory, RAM, AHB and APB peripherals) and ensures a seamless and efficient operation even when several high-speed peripherals work simultaneously.

Figure 4. Multi-AHB matrix



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### 3.8 DMA controller (DMA)

The devices feature two general-purpose dual-port DMAs (DMA1 and DMA2) with 8 streams each. They are able to manage memory-to-memory, peripheral-to-memory and memory-to-peripheral transfers. They feature dedicated FIFOs for APB/AHB peripherals, support burst transfer and are designed to provide the maximum peripheral bandwidth (AHB/APB).

The two DMA controllers support circular buffer management, so that no specific code is needed when the controller reaches the end of the buffer. The two DMA controllers also have a double buffering feature, which automates the use and switching of two memory buffers without requiring any special code.

Each stream is connected to dedicated hardware DMA requests, with support for software trigger on each stream. Configuration is made by software and transfer sizes between source and destination are independent.

The DMA can be used with the main peripherals:

- SPI and I<sup>2</sup>S
- I<sup>2</sup>C
- USART
- General-purpose, basic and advanced-control timers TIMx
- SD/SDIO/MMC host interface
- ADC

### 3.9 Nested vectored interrupt controller (NVIC)

The devices embed a nested vectored interrupt controller able to manage 16 priority levels, and handle up to 62 maskable interrupt channels plus the 16 interrupt lines of the Cortex<sup>®</sup>-M4 with FPU.

- Closely coupled NVIC gives low-latency interrupt processing
- Interrupt entry vector table address passed directly to the core
- Allows early processing of interrupts
- Processing of late arriving, higher-priority interrupts
- Support tail chaining
- Processor state automatically saved
- Interrupt entry restored on interrupt exit with no instruction overhead

This hardware block provides flexible interrupt management features with minimum interrupt latency.

### 3.10 External interrupt/event controller (EXTI)

The external interrupt/event controller consists of 21 edge-detector lines used to generate interrupt/event requests. Each line can be independently configured to select the trigger event (rising edge, falling edge, both) and can be masked independently. A pending register maintains the status of the interrupt requests. The EXTI can detect an external line with a pulse width shorter than the Internal APB2 clock period. Up to 81 GPIOs can be connected to the 16 external interrupt lines.

### 3.11 Clocks and startup

On reset the 16 MHz internal RC oscillator is selected as the default CPU clock. The 16 MHz internal RC oscillator is factory-trimmed to offer 1% accuracy at 25 °C. The application can then select as system clock either the RC oscillator or an external 4-26 MHz clock source. This clock can be monitored for failure. If a failure is detected, the system automatically switches back to the internal RC oscillator and a software interrupt is generated (if enabled). This clock source is input to a PLL thus allowing to increase the frequency up to 84 MHz. Similarly, full interrupt management of the PLL clock entry is available when necessary (for example if an indirectly used external oscillator fails).

Several prescalers allow the configuration of the two AHB buses, the high-speed APB (APB2) and the low-speed APB (APB1) domains. The maximum frequency of the two AHB buses is 84 MHz while the maximum frequency of the high-speed APB domains is 84 MHz. The maximum allowed frequency of the low-speed APB domain is 42 MHz.

The devices embed a dedicated PLL (PLL12S) which allows to achieve audio class performance. In this case, the I<sup>2</sup>S master clock can generate all standard sampling frequencies from 8 kHz to 192 kHz.



### 3.12 Boot modes

At startup, boot pins are used to select one out of three boot options:

- Boot from user Flash
- Boot from system memory
- Boot from embedded SRAM

The boot loader is located in system memory. It is used to reprogram the Flash memory by using either USART1(PA9/10), USART2(PD5/6), USB OTG FS in device mode (PA11/12) through DFU (device firmware upgrade), I2C1(PB6/7), I2C2(PB10/3), I2C3(PA8/PB4), SPI1(PA4/5/6/7), SPI2(PB12/13/14/15) or SPI3(PA15, PC10/11/12).

For more detailed information on the bootloader, refer to Application Note: AN2606, *STM32™ microcontroller system memory boot mode*.

### 3.13 Power supply schemes

- $V_{DD} = 1.7$  to  $3.6$  V: external power supply for I/Os with the internal supervisor (POR/PDR) disabled, provided externally through  $V_{DD}$  pins. Requires the use of an external power supply supervisor connected to the  $V_{DD}$  and  $PDR\_ON$  pins.
- $V_{DD} = 1.8$  to  $3.6$  V: external power supply for I/Os and the internal regulator (when enabled), provided externally through  $V_{DD}$  pins.
- $V_{SSA}, V_{DDA} = 1.7$  to  $3.6$  V: external analog power supplies for ADC, Reset blocks, RCs and PLL.  $V_{DDA}$  and  $V_{SSA}$  must be connected to  $V_{DD}$  and  $V_{SS}$ , respectively, with decoupling technique.
- $V_{BAT} = 1.65$  to  $3.6$  V: power supply for RTC, external clock 32 kHz oscillator and backup registers (through power switch) when  $V_{DD}$  is not present.

Refer to [Figure 18: Power supply scheme](#) for more details.

### 3.14 Power supply supervisor

#### 3.14.1 Internal reset ON

This feature is available for  $V_{DD}$  operating voltage range 1.8 V to 3.6 V.

The internal power supply supervisor is enabled by holding PDR\_ON high.

The device has an integrated power-on reset (POR) / power-down reset (PDR) circuitry coupled with a Brownout reset (BOR) circuitry. At power-on, POR is always active, and ensures proper operation starting from 1.8 V. After the 1.8 V POR threshold level is reached, the option byte loading process starts, either to confirm or modify default thresholds, or to disable BOR permanently. Three BOR thresholds are available through option bytes.

The device remains in reset mode when  $V_{DD}$  is below a specified threshold,  $V_{POR/PDR}$  or  $V_{BOR}$ , without the need for an external reset circuit.

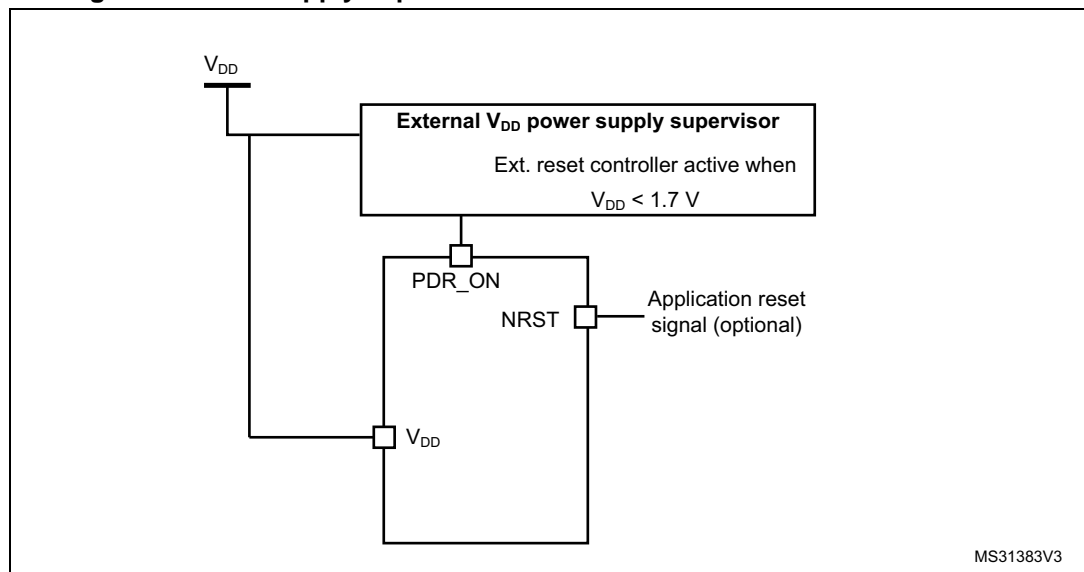
The device also features an embedded programmable voltage detector (PVD) that monitors the  $V_{DD}/V_{DDA}$  power supply and compares it to the  $V_{PVD}$  threshold. An interrupt can be generated when  $V_{DD}/V_{DDA}$  drops below the  $V_{PVD}$  threshold and/or when  $V_{DD}/V_{DDA}$  is higher than the  $V_{PVD}$  threshold. The interrupt service routine can then generate a warning message and/or put the MCU into a safe state. The PVD is enabled by software.

#### 3.14.2 Internal reset OFF

This feature is available only on packages featuring the PDR\_ON pin. The internal power-on reset (POR) / power-down reset (PDR) circuitry is disabled by setting the PDR\_ON pin to low.

An external power supply supervisor should monitor  $V_{DD}$  and should maintain the device in reset mode as long as  $V_{DD}$  is below a specified threshold. PDR\_ON should be connected to this external power supply supervisor. Refer to [Figure 5: Power supply supervisor interconnection with internal reset OFF](#).

Figure 5. Power supply supervisor interconnection with internal reset OFF<sup>(1)</sup>



1. The PRD\_ON pin is only available in the WLCS49 and UFBGA100 packages.

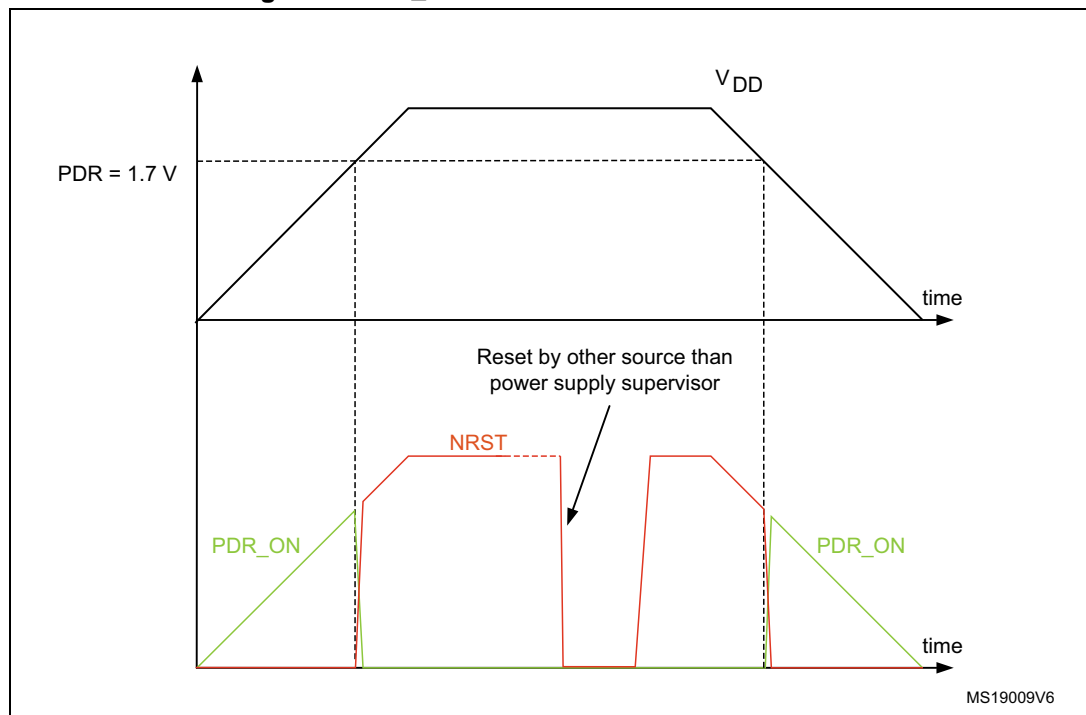
The  $V_{DD}$  specified threshold, below which the device must be maintained under reset, is 1.7 V (see [Figure 6](#)).

A comprehensive set of power-saving mode allows to design low-power applications.

When the internal reset is OFF, the following integrated features are no longer supported:

- The integrated power-on reset (POR) / power-down reset (PDR) circuitry is disabled.
- The brownout reset (BOR) circuitry must be disabled.
- The embedded programmable voltage detector (PVD) is disabled.
- $V_{BAT}$  functionality is no more available and VBAT pin should be connected to  $V_{DD}$ .

**Figure 6. PDR\_ON control with internal reset OFF**



### 3.15 Voltage regulator

The regulator has four operating modes:

- Regulator ON
  - Main regulator mode (MR)
  - Low power regulator (LPR)
  - Power-down
- Regulator OFF

#### 3.15.1 Regulator ON

On packages embedding the BYPASS\_REG pin, the regulator is enabled by holding BYPASS\_REG low. On all other packages, the regulator is always enabled.

There are three power modes configured by software when the regulator is ON:

- MR is used in the nominal regulation mode (With different voltage scaling in Run)  
In Main regulator mode (MR mode), different voltage scaling are provided to reach the best compromise between maximum frequency and dynamic power consumption.
- LPR is used in the Stop modes  
The LP regulator mode is configured by software when entering Stop mode.
- Power-down is used in Standby mode.  
The Power-down mode is activated only when entering in Standby mode. The regulator output is in high impedance and the kernel circuitry is powered down, inducing zero consumption. The contents of the registers and SRAM are lost.

Depending on the package, one or two external ceramic capacitors should be connected on the  $V_{CAP\_1}$  and  $V_{CAP\_2}$  pins. The  $V_{CAP\_2}$  pin is only available for the LQFP100 and UFBGA100 packages.

All packages have the regulator ON feature.

### 3.15.2 Regulator OFF

The Regulator OFF is available only on the UFBGA100, which features the `BYPASS_REG` pin. The regulator is disabled by holding `BYPASS_REG` high. The regulator OFF mode allows to supply externally a V12 voltage source through  $V_{CAP\_1}$  and  $V_{CAP\_2}$  pins.

Since the internal voltage scaling is not managed internally, the external voltage value must be aligned with the targeted maximum frequency. Refer to [Table 14: General operating conditions](#).

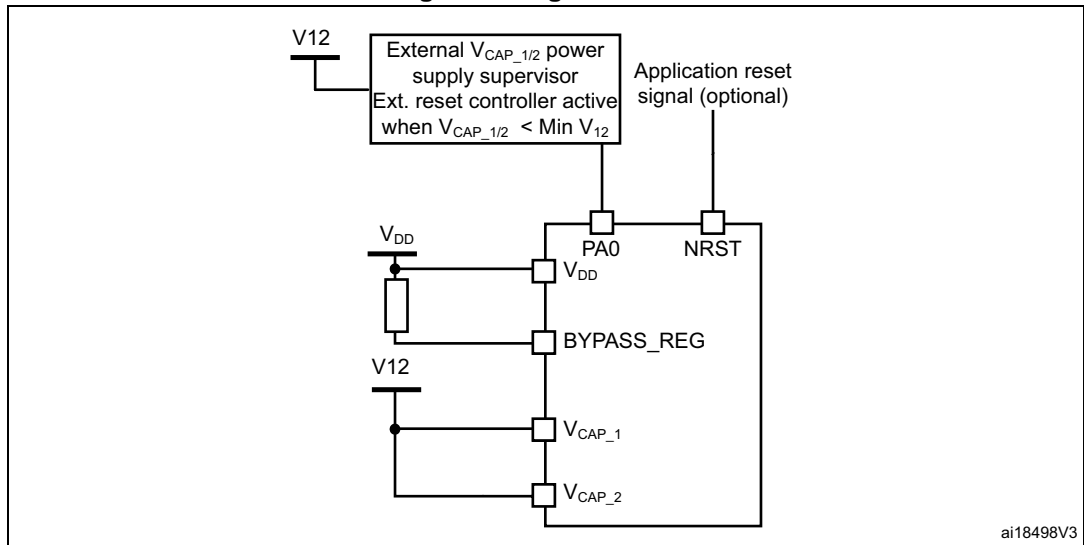
The two 2.2  $\mu\text{F}$   $V_{CAP}$  ceramic capacitors should be replaced by two 100 nF decoupling capacitors. Refer to [Figure 18: Power supply scheme](#).

When the regulator is OFF, there is no more internal monitoring on V12. An external power supply supervisor should be used to monitor the V12 of the logic power domain. PA0 pin should be used for this purpose, and act as power-on reset on V12 power domain.

In regulator OFF mode, the following features are no more supported:

- PA0 cannot be used as a GPIO pin since it allows to reset a part of the V12 logic power domain which is not reset by the NRST pin.
- As long as PA0 is kept low, the debug mode cannot be used under power-on reset. As a consequence, PA0 and NRST pins must be managed separately if the debug connection under reset or pre-reset is required.

Figure 7. Regulator OFF

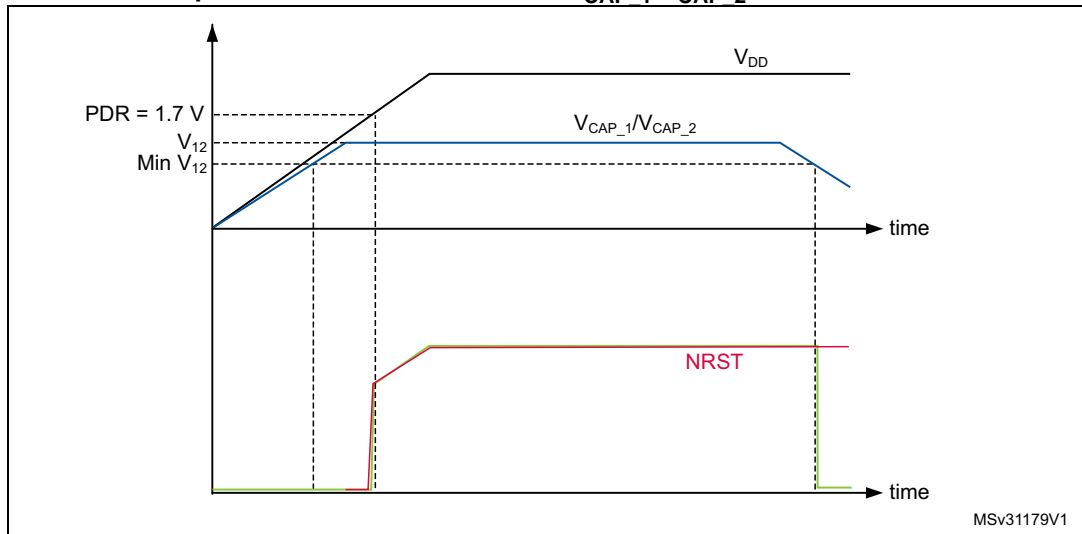


The following conditions must be respected:

- $V_{DD}$  should always be higher than  $V_{CAP\_1}$  and  $V_{CAP\_2}$  to avoid current injection between power domains.
- If the time for  $V_{CAP\_1}$  and  $V_{CAP\_2}$  to reach  $V_{12}$  minimum value is faster than the time for  $V_{DD}$  to reach 1.7 V, then PA0 should be kept low to cover both conditions: until  $V_{CAP\_1}$  and  $V_{CAP\_2}$  reach  $V_{12}$  minimum value and until  $V_{DD}$  reaches 1.7 V (see [Figure 8](#)).
- Otherwise, if the time for  $V_{CAP\_1}$  and  $V_{CAP\_2}$  to reach  $V_{12}$  minimum value is slower than the time for  $V_{DD}$  to reach 1.7 V, then PA0 could be asserted low externally (see [Figure 9](#)).
- If  $V_{CAP\_1}$  and  $V_{CAP\_2}$  go below  $V_{12}$  minimum value and  $V_{DD}$  is higher than 1.7 V, then a reset must be asserted on PA0 pin.

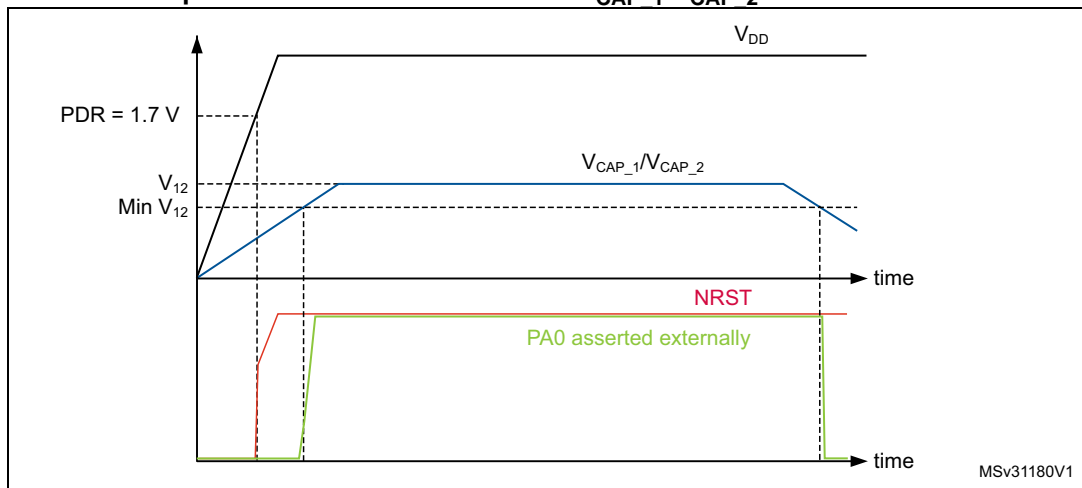
*Note:* The minimum value of  $V_{12}$  depends on the maximum frequency targeted in the application

**Figure 8. Startup in regulator OFF: slow  $V_{DD}$  slope - power-down reset risen after  $V_{CAP\_1}/V_{CAP\_2}$  stabilization**



1. This figure is valid whatever the internal reset mode (ON or OFF).

**Figure 9. Startup in regulator OFF mode: fast  $V_{DD}$  slope - power-down reset risen before  $V_{CAP\_1}/V_{CAP\_2}$  stabilization**



1. This figure is valid whatever the internal reset mode (ON or OFF).

### 3.15.3 Regulator ON/OFF and internal power supply supervisor availability

Table 3. Regulator ON/OFF and internal power supply supervisor availability

Package	Regulator ON	Regulator OFF	Power supply supervisor ON	Power supply supervisor OFF
UFQFPN48	Yes	No	Yes	No
WLCSP49	Yes	No	Yes PDR_ON set to VDD	Yes PDR_ON external control <sup>(1)</sup>
LQFP64	Yes	No	Yes	No
LQFP100	Yes	No	Yes	No
UFBGA100	Yes BYPASS_REG set to VSS	Yes BYPASS_REG set to VDD	Yes PDR_ON set to VDD	Yes PDR_ON external control <sup>(1)</sup>

1. Refer to [Section 3.14: Power supply supervisor](#)

### 3.16 Real-time clock (RTC) and backup registers

The backup domain includes:

- The real-time clock (RTC)
- 20 backup registers

The real-time clock (RTC) is an independent BCD timer/counter. Dedicated registers contain the second, minute, hour (in 12/24 hour), week day, date, month, year, in BCD (binary-coded decimal) format. Correction for 28, 29 (leap year), 30, and 31 day of the month are performed automatically. The RTC features a reference clock detection, a more precise second source clock (50 or 60 Hz) can be used to enhance the calendar precision. The RTC provides a programmable alarm and programmable periodic interrupts with wakeup from Stop and Standby modes. The sub-seconds value is also available in binary format.

It is clocked by a 32.768 kHz external crystal, resonator or oscillator, the internal low-power RC oscillator or the high-speed external clock divided by 128. The internal low-speed RC has a typical frequency of 32 kHz. The RTC can be calibrated using an external 512 Hz output to compensate for any natural quartz deviation.

Two alarm registers are used to generate an alarm at a specific time and calendar fields can be independently masked for alarm comparison. To generate a periodic interrupt, a 16-bit programmable binary auto-reload downcounter with programmable resolution is available and allows automatic wakeup and periodic alarms from every 120 μs to every 36 hours.

A 20-bit prescaler is used for the time base clock. It is by default configured to generate a time base of 1 second from a clock at 32.768 kHz.

The backup registers are 32-bit registers used to store 80 bytes of user application data when V<sub>DD</sub> power is not present. Backup registers are not reset by a system, a power reset, or when the device wakes up from the Standby mode (see [Section 3.17: Low-power modes](#)).

Additional 32-bit registers contain the programmable alarm subseconds, seconds, minutes, hours, day, and date.

The RTC and backup registers are supplied through a switch that is powered either from the  $V_{DD}$  supply when present or from the  $V_{BAT}$  pin.

### 3.17 Low-power modes

The devices support three low-power modes to achieve the best compromise between low power consumption, short startup time and available wakeup sources:

- **Sleep mode**

In Sleep mode, only the CPU is stopped. All peripherals continue to operate and can wake up the CPU when an interrupt/event occurs.

- **Stop mode**

The Stop mode achieves the lowest power consumption while retaining the contents of SRAM and registers. All clocks in the 1.2 V domain are stopped, the PLL, the HSI RC and the HSE crystal oscillators are disabled. The voltage regulator can also be put either in normal or in low-power mode.

The device can be woken up from the Stop mode by any of the EXTI line (the EXTI line source can be one of the 16 external lines, the PVD output, the RTC alarm/ wakeup/ tamper/ time stamp events).

- **Standby mode**

The Standby mode is used to achieve the lowest power consumption. The internal voltage regulator is switched off so that the entire 1.2 V domain is powered off. The PLL, the HSI RC and the HSE crystal oscillators are also switched off. After entering Standby mode, the SRAM and register contents are lost except for registers in the backup domain when selected.

The device exits the Standby mode when an external reset (NRST pin), an IWDG reset, a rising edge on the WKUP pin, or an RTC alarm/ wakeup/ tamper/time stamp event occurs.

Standby mode is not supported when the embedded voltage regulator is bypassed and the 1.2 V domain is controlled by an external power.

### 3.18 $V_{BAT}$ operation

The VBAT pin allows to power the device  $V_{BAT}$  domain from an external battery, an external super-capacitor, or from  $V_{DD}$  when no external battery and an external super-capacitor are present.

$V_{BAT}$  operation is activated when  $V_{DD}$  is not present.

The VBAT pin supplies the RTC and the backup registers.

*Note: When the microcontroller is supplied from VBAT, external interrupts and RTC alarm/events do not exit it from  $V_{BAT}$  operation. When PDR\_ON pin is not connected to  $V_{DD}$  (internal Reset OFF), the  $V_{BAT}$  functionality is no more available and VBAT pin should be connected to  $V_{DD}$ .*



### 3.19 Timers and watchdogs

The devices embed one advanced-control timer, seven general-purpose timers and two watchdog timers.

All timer counters can be frozen in debug mode.

[Table 4](#) compares the features of the advanced-control and general-purpose timers.

**Table 4. Timer feature comparison**

Timer type	Timer	Counter resolution	Counter type	Prescaler factor	DMA request generation	Capture/compare channels	Complementary output	Max. interface clock (MHz)	Max. timer clock (MHz)
Advanced-control	TIM1	16-bit	Up, Down, Up/down	Any integer between 1 and 65536	Yes	4	Yes	84	84
General purpose	TIM2, TIM5	32-bit	Up, Down, Up/down	Any integer between 1 and 65536	Yes	4	No	42	84
	TIM3, TIM4	16-bit	Up, Down, Up/down	Any integer between 1 and 65536	Yes	4	No	42	84
	TIM9	16-bit	Up	Any integer between 1 and 65536	No	2	No	84	84
	TIM10, TIM11	16-bit	Up	Any integer between 1 and 65536	No	1	No	84	84

#### 3.19.1 Advanced-control timers (TIM1)

The advanced-control timer (TIM1) can be seen as three-phase PWM generators multiplexed on 4 independent channels. It has complementary PWM outputs with programmable inserted dead times. It can also be considered as a complete general-purpose timer. Its 4 independent channels can be used for:

- Input capture
- Output compare
- PWM generation (edge- or center-aligned modes)
- One-pulse mode output

If configured as standard 16-bit timers, it has the same features as the general-purpose TIMx timers. If configured as a 16-bit PWM generator, it has full modulation capability (0-100%).

The advanced-control timer can work together with the TIMx timers via the Timer Link feature for synchronization or event chaining.

TIM1 supports independent DMA request generation.

### 3.19.2 General-purpose timers (TIMx)

There are seven synchronizable general-purpose timers embedded in the STM32F401xD/xE (see [Table 4](#) for differences).

- **TIM2, TIM3, TIM4, TIM5**

The STM32F401xD/xE devices are 4 full-featured general-purpose timers: TIM2, TIM5, TIM3, and TIM4. The TIM2 and TIM5 timers are based on a 32-bit auto-reload up/downcounter and a 16-bit prescaler. The TIM3 and TIM4 timers are based on a 16-bit auto-reload up/downcounter and a 16-bit prescaler. They all feature four independent channels for input capture/output compare, PWM or one-pulse mode output. This gives up to 15 input capture/output compare/PWMs.

The TIM2, TIM3, TIM4, TIM5 general-purpose timers can work together, or with the other general-purpose timers and the advanced-control timers TIM1 and TIM8 via the Timer Link feature for synchronization or event chaining.

Any of these general-purpose timers can be used to generate PWM outputs.

TIM2, TIM3, TIM4, TIM5 all have independent DMA request generation. They are capable of handling quadrature (incremental) encoder signals and the digital outputs from 1 to 4 hall-effect sensors.

- **TIM9, TIM10 and TIM11**

These timers are based on a 16-bit auto-reload upcounter and a 16-bit prescaler. TIM10 and TIM11 feature one independent channel, whereas TIM9 has two independent channels for input capture/output compare, PWM or one-pulse mode output. They can be synchronized with the TIM2, TIM3, TIM4, TIM5 full-featured general-purpose timers. They can also be used as simple time bases.

### 3.19.3 Independent watchdog

The independent watchdog is based on a 12-bit downcounter and 8-bit prescaler. It is clocked from an independent 32 kHz internal RC and as it operates independently from the main clock, it can operate in Stop and Standby modes. It can be used either as a watchdog to reset the device when a problem occurs, or as a free-running timer for application timeout management. It is hardware- or software-configurable through the option bytes.

### 3.19.4 Window watchdog

The window watchdog is based on a 7-bit downcounter that can be set as free-running. It can be used as a watchdog to reset the device when a problem occurs. It is clocked from the main clock. It has an early warning interrupt capability and the counter can be frozen in debug mode.

### 3.19.5 SysTick timer

This timer is dedicated to real-time operating systems, but could also be used as a standard downcounter. It features:

- A 24-bit downcounter
- Autoreload capability
- Maskable system interrupt generation when the counter reaches 0
- Programmable clock source.

### 3.20 Inter-integrated circuit interface (I<sup>2</sup>C)

Up to three I<sup>2</sup>C bus interfaces can operate in multimaster and slave modes. They can support the standard (up to 100 kHz) and fast (up to 400 kHz) modes. The I2C bus frequency can be increased up to 1 MHz. For more details about the complete solution, please contact your local ST sales representative. They also support the 7/10-bit addressing mode and the 7-bit dual addressing mode (as slave). A hardware CRC generation/verification is embedded.

They can be served by DMA and they support SMBus 2.0/PMBus.

The devices also include programmable analog and digital noise filters (see [Table 5](#)).

**Table 5. Comparison of I2C analog and digital filters**

	Analog filter	Digital filter
Pulse width of suppressed spikes	≥ 50 ns	Programmable length from 1 to 15 I2C peripheral clocks

### 3.21 Universal synchronous/asynchronous receiver transmitters (USART)

The devices embed three universal synchronous/asynchronous receiver transmitters (USART1, USART2 and USART6).

These three interfaces provide asynchronous communication, IrDA SIR ENDEC support, multiprocessor communication mode, single-wire half-duplex communication mode and have LIN Master/Slave capability. The USART1 and USART6 interfaces are able to communicate at speeds of up to 10.5 Mbit/s. The USART2 interface communicates at up to 5.25 bit/s.

USART1 and USART2 also provide hardware management of the CTS and RTS signals, Smart Card mode (ISO 7816 compliant) and SPI-like communication capability. All interfaces can be served by the DMA controller.

Table 6. USART feature comparison

USART name	Standard features	Modem (RTS/CTS)	LIN	SPI master	IrDA	Smartcard (ISO 7816)	Max. baud rate in Mbit/s (oversampling by 16)	Max. baud rate in Mbit/s (oversampling by 8)	APB mapping
USART1	X	X	X	X	X	X	5.25	10.5	APB2 (max. 84 MHz)
USART2	X	X	X	X	X	X	2.62	5.25	APB1 (max. 42 MHz)
USART6	X	N.A	X	X	X	X	5.25	10.5	APB2 (max. 84 MHz)

### 3.22 Serial peripheral interface (SPI)

The devices feature up to four SPIs in slave and master modes in full-duplex and simplex communication modes. SPI1 and SPI4 can communicate at up to 42 Mbit/s, SPI2 and SPI3 can communicate at up to 21 Mbit/s. The 3-bit prescaler gives 8 master mode frequencies and the frame is configurable to 8 bits or 16 bits. The hardware CRC generation/verification supports basic SD Card/MMC modes. All SPIs can be served by the DMA controller.

The SPI interface can be configured to operate in TI mode for communications in master mode and slave mode.

### 3.23 Inter-integrated sound (I<sup>2</sup>S)

Two standard I<sup>2</sup>S interfaces (multiplexed with SPI2 and SPI3) are available. They can be operated in master or slave mode, in full duplex and simplex communication modes and can be configured to operate with a 16-/32-bit resolution as an input or output channel. Audio sampling frequencies from 8 kHz up to 192 kHz are supported. When either or both of the I<sup>2</sup>S interfaces is/are configured in master mode, the master clock can be output to the external DAC/CODEC at 256 times the sampling frequency.

All I<sup>2</sup>Sx can be served by the DMA controller.

### 3.24 Audio PLL (PLLI2S)

The devices feature an additional dedicated PLL for audio I<sup>2</sup>S application. It allows to achieve error-free I<sup>2</sup>S sampling clock accuracy without compromising on the CPU performance.

The PLLI2S configuration can be modified to manage an I<sup>2</sup>S sample rate change without disabling the main PLL (PLL) used for the CPU.

The audio PLL can be programmed with very low error to obtain sampling rates ranging from 8 kHz to 192 kHz.

In addition to the audio PLL, a master clock input pin can be used to synchronize the I<sup>2</sup>S flow with an external PLL (or Codec output).

### 3.25 Secure digital input/output interface (SDIO)

An SD/SDIO/MMC host interface is available, that supports MultiMediaCard System Specification Version 4.2 in three different databus modes: 1-bit (default), 4-bit and 8-bit.

The interface allows data transfer at up to 48 MHz, and is compliant with the SD Memory Card Specification Version 2.0.

The SDIO Card Specification Version 2.0 is also supported with two different databus modes: 1-bit (default) and 4-bit.

The current version supports only one SD/SDIO/MMC4.2 card at any one time and a stack of MMC4.1 or previous.

In addition to SD/SDIO/MMC, this interface is fully compliant with the CE-ATA digital protocol Rev1.1.

### 3.26 Universal serial bus on-the-go full-speed (OTG\_FS)

The devices embed an USB OTG full-speed device/host/OTG peripheral with integrated transceivers. The USB OTG FS peripheral is compliant with the USB 2.0 specification and with the OTG 1.0 specification. It has software-configurable endpoint setting and supports suspend/resume. The USB OTG full-speed controller requires a dedicated 48 MHz clock that is generated by a PLL connected to the HSE oscillator. The major features are:

- Combined Rx and Tx FIFO size of 320 x 35 bits with dynamic FIFO sizing
- Supports the session request protocol (SRP) and host negotiation protocol (HNP)
- 4 bidirectional endpoints
- 8 host channels with periodic OUT support
- HNP/SNP/IP inside (no need for any external resistor)
- For OTG/Host modes, a power switch is needed in case bus-powered devices are connected

### 3.27 General-purpose input/outputs (GPIOs)

Each of the GPIO pins can be configured by software as output (push-pull or open-drain, with or without pull-up or pull-down), as input (floating, with or without pull-up or pull-down) or as peripheral alternate function. Most of the GPIO pins are shared with digital or analog alternate functions. All GPIOs are high-current-capable and have speed selection to better manage internal noise, power consumption and electromagnetic emission.

The I/O configuration can be locked if needed by following a specific sequence in order to avoid spurious writing to the I/Os registers.

Fast I/O handling allowing maximum I/O toggling up to 84 MHz.

### 3.28 Analog-to-digital converter (ADC)

One 12-bit analog-to-digital converter is embedded and shares up to 16 external channels, performing conversions in the single-shot or scan mode. In scan mode, automatic conversion is performed on a selected group of analog inputs.

The ADC can be served by the DMA controller. An analog watchdog feature allows very precise monitoring of the converted voltage of one, some or all selected channels. An interrupt is generated when the converted voltage is outside the programmed thresholds.

To synchronize A/D conversion and timers, the ADCs could be triggered by any of TIM1, TIM2, TIM3, TIM4 or TIM5 timer.

### 3.29 Temperature sensor

The temperature sensor has to generate a voltage that varies linearly with temperature. The conversion range is between 1.7 V and 3.6 V. The temperature sensor is internally connected to the ADC\_IN16 input channel which is used to convert the sensor output voltage into a digital value. Refer to the reference manual for additional information.

As the offset of the temperature sensor varies from chip to chip due to process variation, the internal temperature sensor is mainly suitable for applications that detect temperature changes instead of absolute temperatures. If an accurate temperature reading is needed, then an external temperature sensor part should be used.

### 3.30 Serial wire JTAG debug port (SWJ-DP)

The ARM SWJ-DP interface is embedded, and is a combined JTAG and serial wire debug port that enables either a serial wire debug or a JTAG probe to be connected to the target.

Debug is performed using 2 pins only instead of 5 required by the JTAG (JTAG pins could be re-use as GPIO with alternate function): the JTAG TMS and TCK pins are shared with SWDIO and SWCLK, respectively, and a specific sequence on the TMS pin is used to switch between JTAG-DP and SW-DP.

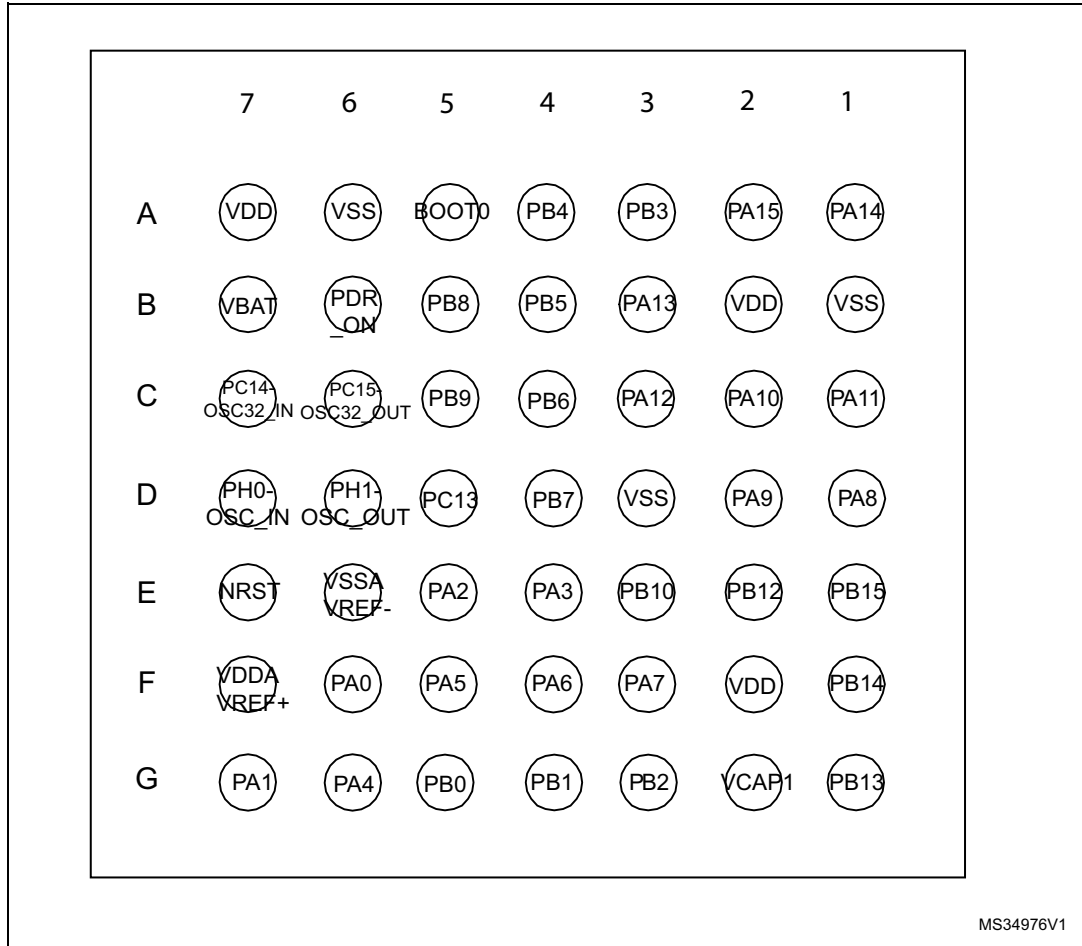
### 3.31 Embedded Trace Macrocell™

The ARM Embedded Trace Macrocell provides a greater visibility of the instruction and data flow inside the CPU core by streaming compressed data at a very high rate from the STM32F401xD/xE through a small number of ETM pins to an external hardware trace port analyzer (TPA) device. The TPA is connected to a host computer using any high-speed channel available. Real-time instruction and data flow activity can be recorded and then formatted for display on the host computer that runs the debugger software. TPA hardware is commercially available from common development tool vendors.

The Embedded Trace Macrocell operates with third party debugger software tools.

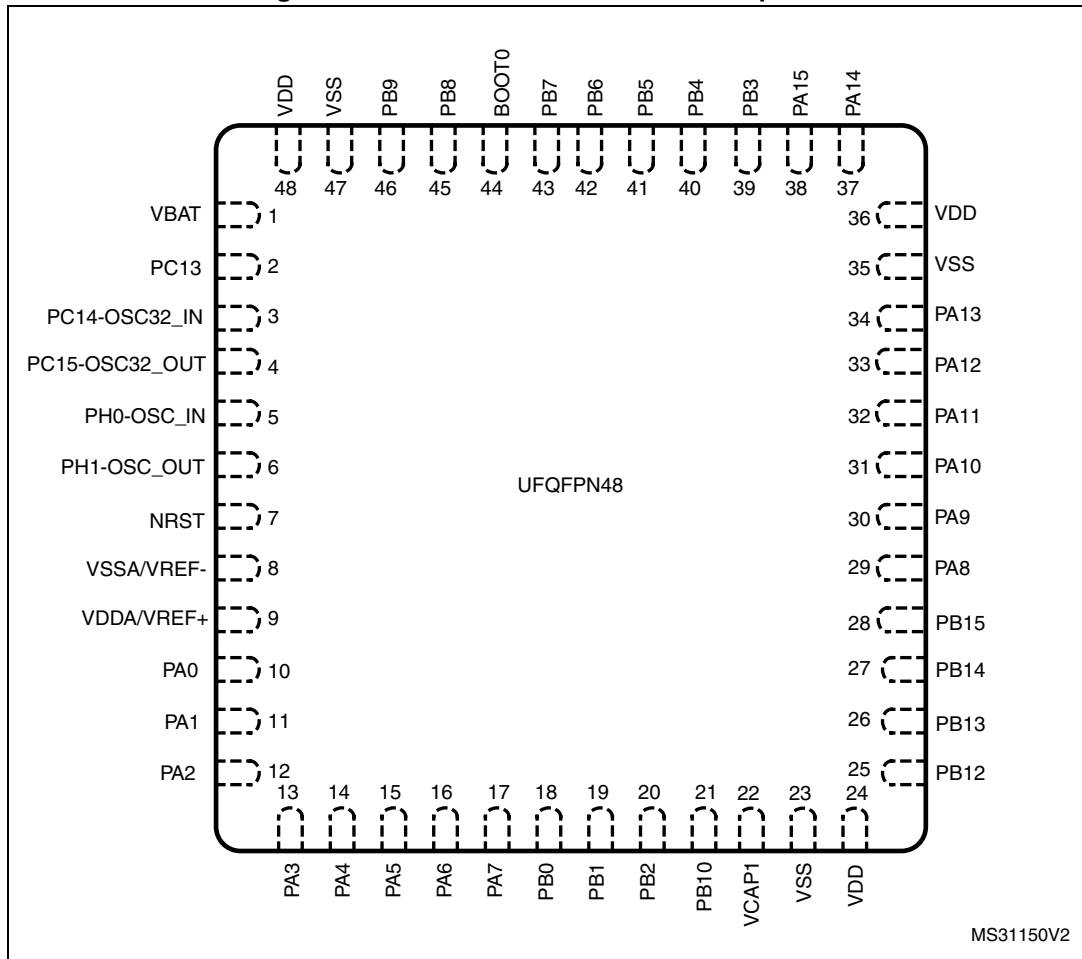
## 4 Pinouts and pin description

Figure 10. STM32F401xD/xE WLCSP49 pinout



1. The above figure shows the package bump side.

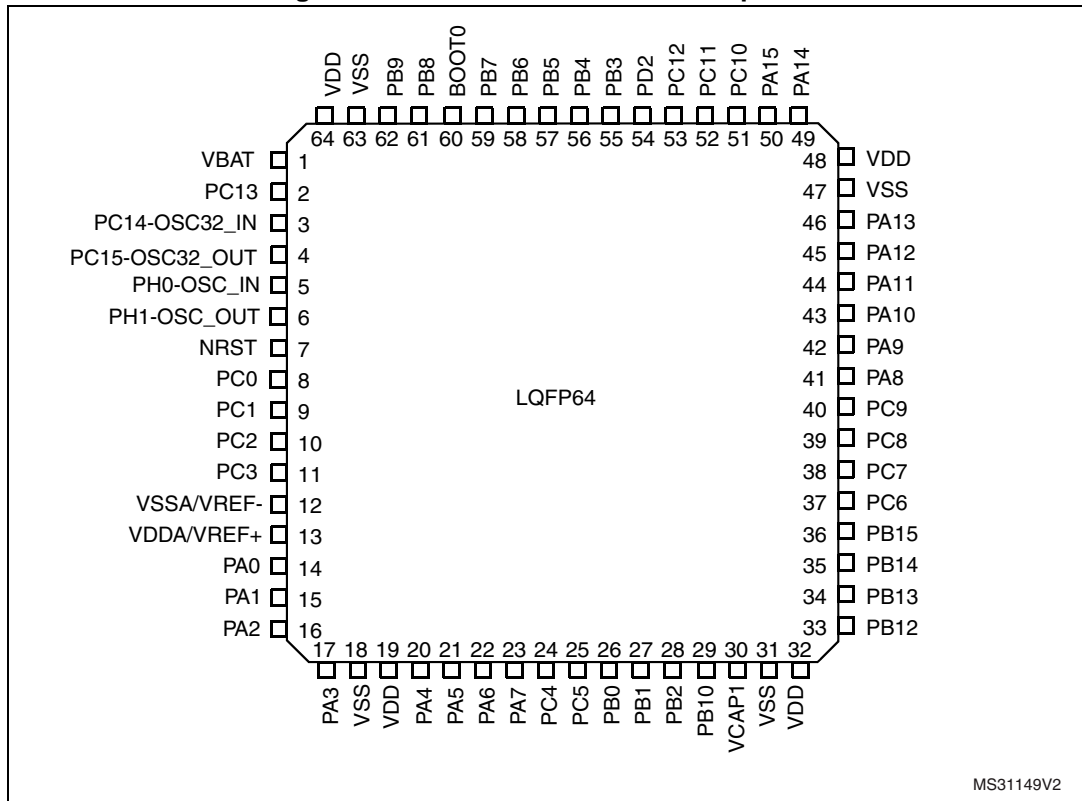
Figure 11. STM32F401xD/xE UFQFPN48 pinout



1. The above figure shows the package top view.



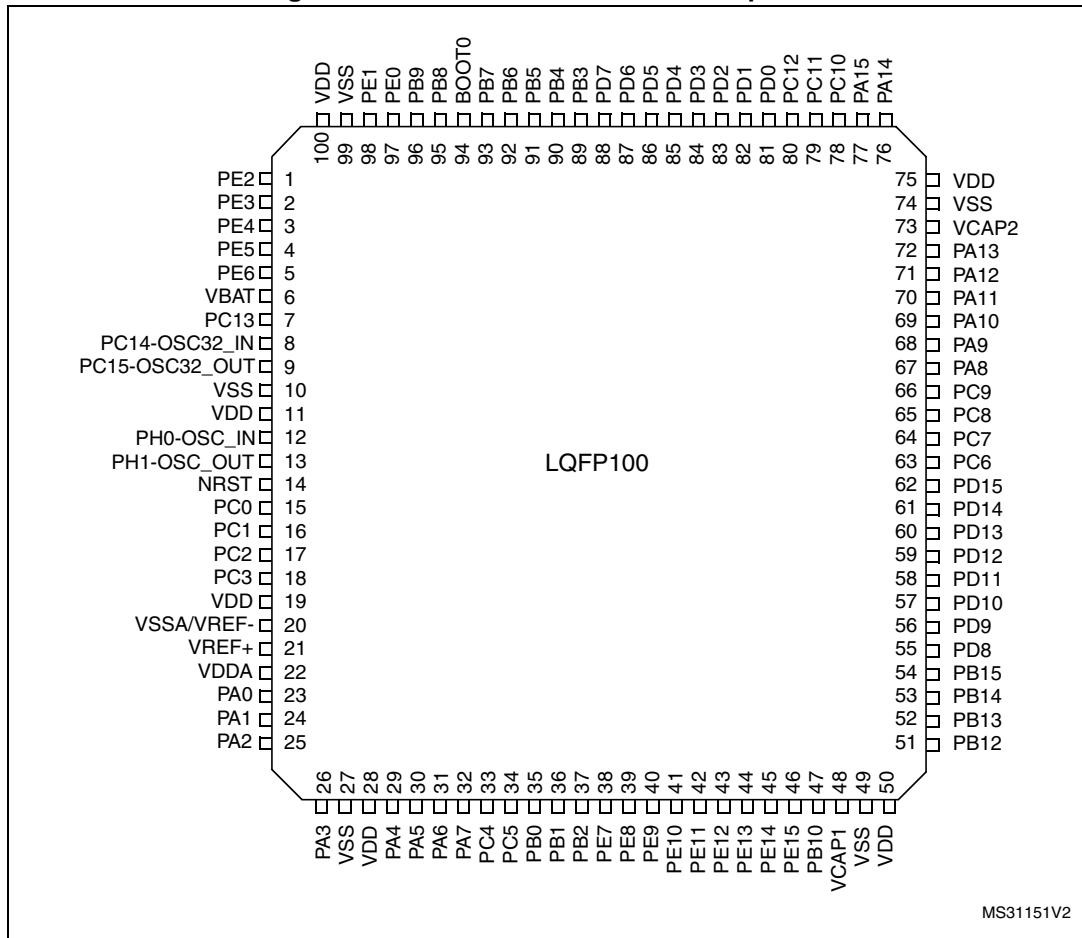
Figure 12. STM32F401xD/xE LQFP64 pinout



MS31149V2

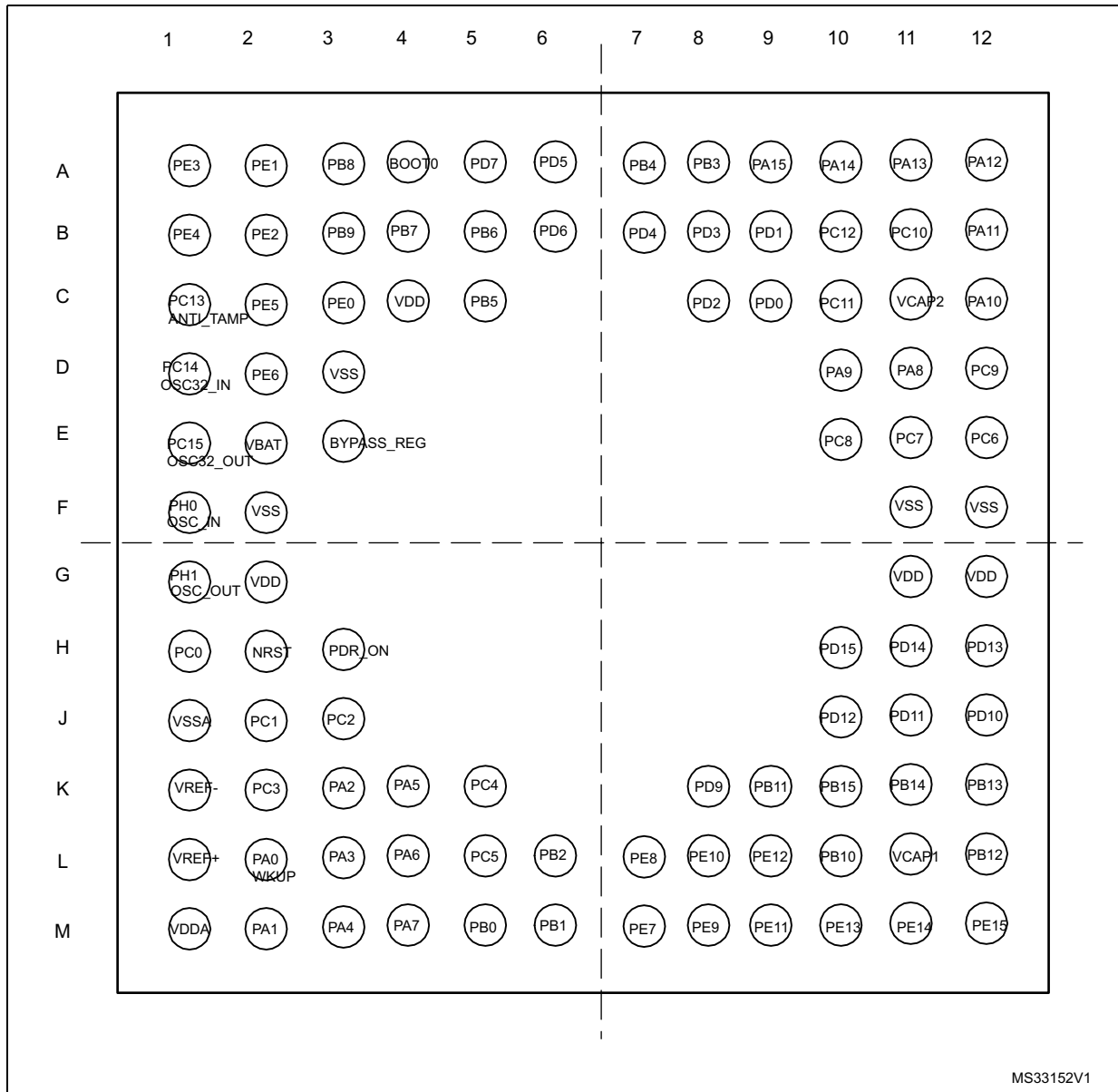
1. The above figure shows the package top view.

Figure 13. STM32F401xD/xE LQFP100 pinout



1. The above figure shows the package top view.

Figure 14. STM32F401xD/xE UFBGA100 pinout



MS33152V1

1. This figure shows the package top view

**Table 7. Legend/abbreviations used in the pinout table**

Name	Abbreviation	Definition
Pin name	Unless otherwise specified in brackets below the pin name, the pin function during and after reset is the same as the actual pin name	
Pin type	S	Supply pin
	I	Input only pin
	I/O	Input/ output pin
I/O structure	FT	5 V tolerant I/O
	B	Dedicated BOOT0 pin
	NRST	Bidirectional reset pin with embedded weak pull-up resistor
Notes	Unless otherwise specified by a note, all I/Os are set as floating inputs during and after reset	
Alternate functions	Functions selected through GPIOx_AFR registers	
Additional functions	Functions directly selected/enabled through peripheral registers	

**Table 8. STM32F401xD/xE pin definitions**

Pin Number					Pin name (function after reset) <sup>(1)</sup>	Pin type	I/O structure	Notes	Alternate functions	Additional functions
UQFN48	WLCSP49	LQFP64	LQFP100	UFBGA100						
-	-	-	1	B2	PE2	I/O	FT	-	SPI4_SCK, TRACECLK, EVENTOUT	-
-	-	-	2	A1	PE3	I/O	FT	-	TRACED0, EVENTOUT	-
-	-	-	3	B1	PE4	I/O	FT	-	SPI4_NSS, TRACED1, EVENTOUT	-
-	-	-	4	C2	PE5	I/O	FT	-	SPI4_MISO, TIM9_CH1, TRACED2, EVENTOUT	-
-	-	-	5	D2	PE6	I/O	FT	-	SPI4_MOSI, TIM9_CH2, TRACED3, EVENTOUT	-
-	-	-	-	D3	VSS	S	-	-	-	-
-	-	-	-	C4	VDD	S	-	-	-	-
1	B7	1	6	E2	VBAT	S	-	-	-	-
2	D5	2	7	C1	PC13	I/O	FT	(2) (3)	EVENTOUT,	RTC_TAMP1, RTC_OUT, RTC_TS

Table 8. STM32F401xD/xE pin definitions (continued)

Pin Number					Pin name (function after reset) <sup>(1)</sup>	Pin type	I/O structure	Notes	Alternate functions	Additional functions
UQFN48	WLCSP49	LQFP64	LQFP100	UFBGA100						
3	C7	3	8	D1	PC14-OSC32_IN (PC14)	I/O	FT	(2) (3) (4)	EVENTOUT	OSC32_IN
4	C6	4	9	E1	PC15-OSC32_OUT (PC15)	I/O	FT	(2) (3) (4)	EVENTOUT	OSC32_OUT
-	-	-	10	F2	VSS	S	-	-	-	-
-	-	-	11	G2	VDD	S	-	-	-	-
5	D7	5	12	F1	PH0-OSC_IN (PH0)	I/O	FT	(4)	EVENTOUT	OSC_IN
6	D6	6	13	G1	PH1-OSC_OUT (PH1)	I/O	FT	(4)	EVENTOUT	OSC_OUT
7	E7	7	14	H2	NRST	I/O	FT	-	EVENTOUT	-
-	-	8	15	H1	PC0	I/O	FT	-	EVENTOUT	ADC1_IN10
-	-	9	16	J2	PC1	I/O	FT	-	EVENTOUT	ADC1_IN11
-	-	10	17	J3	PC2	I/O	FT	-	SPI2_MISO, I2S2ext_SD, EVENTOUT	ADC1_IN12
-	-	11	18	K2	PC3	I/O	FT	-	SPI2_MOSI/I2S2_SD, EVENTOUT	ADC1_IN13
-	-	-	19	-	VDD	S	-	-	-	-
8	E6	12	20	-	VSSA/VREF-	S	-	-	-	-
-	-	-	-	J1	VSSA	S	-	-	-	-
-	-	-	-	K1	VREF-	S	-	-	-	-
9	-	13	-	-	VDDA/VREF+	S	-	-	-	-
-	-	-	21	L1	VREF+	S	-	-	-	-
-	F7	-	22	M1	VDDA	S	-	-	-	-
10	F6	14	23	L2	PA0	I/O	FT	(5)	USART2_CTS, TIM2_CH1/TIM2_ETR, TIM5_CH1, EVENTOUT	ADC1_IN0, WKUP
11	G7	15	24	M2	PA1	I/O	FT	-	USART2_RTS, TIM2_CH2, TIM5_CH2, EVENTOUT	ADC1_IN1
12	E5	16	25	K3	PA2	I/O	FT	-	USART2_TX, TIM2_CH3, TIM5_CH3, TIM9_CH1, EVENTOUT	ADC1_IN2

Table 8. STM32F401xD/xE pin definitions (continued)

Pin Number					Pin name (function after reset) <sup>(1)</sup>	Pin type	I/O structure	Notes	Alternate functions	Additional functions
UQFN48	WLCSP49	LQFP64	LQFP100	UFBGA100						
13	E4	17	26	L3	PA3	I/O	FT	-	USART2_RX, TIM2_CH4, TIM5_CH4, TIM9_CH2, EVENTOUT	ADC1_IN3
-	-	18	27	-	VSS	S	-	-	-	-
-	-	19	28	-	VDD	S	-	-	-	-
-	-	-	-	E3	BYPASS_REG	I	FT	-	-	-
14	G6	20	29	M3	PA4	I/O	FT	-	SPI1_NSS, SPI3_NSS/I2S3_WS, USART2_CK, EVENTOUT	ADC1_IN4
15	F5	21	30	K4	PA5	I/O	FT	-	SPI1_SCK, TIM2_CH1/TIM2_ETR, EVENTOUT	ADC1_IN5
16	F4	22	31	L4	PA6	I/O	FT	-	SPI1_MISO, TIM1_BKIN, TIM3_CH1, EVENTOUT	ADC1_IN6
17	F3	23	32	M4	PA7	I/O	FT	-	SPI1_MOSI, TIM1_CH1N, TIM3_CH2, EVENTOUT	ADC1_IN7
-	-	24	33	K5	PC4	I/O	FT	-	EVENTOUT	ADC1_IN14
-	-	25	34	L5	PC5	I/O	FT	-	EVENTOUT	ADC1_IN15
18	G5	26	35	M5	PB0	I/O	FT	-	TIM1_CH2N, TIM3_CH3, EVENTOUT	ADC1_IN8
19	G4	27	36	M6	PB1	I/O	FT	-	TIM1_CH3N, TIM3_CH4, EVENTOUT	ADC1_IN9
20	G3	28	37	L6	PB2	I/O	FT	-	EVENTOUT	BOOT1
-	-	-	38	M7	PE7	I/O	FT	-	TIM1_ETR, EVENTOUT	-
-	-	-	39	L7	PE8	I/O	FT	-	TIM1_CH1N, EVENTOUT	-
-	-	-	40	M8	PE9	I/O	FT	-	TIM1_CH1, EVENTOUT	-
-	-	-	41	L8	PE10	I/O	FT	-	TIM1_CH2N, EVENTOUT	-
-	-	-	42	M9	PE11	I/O	FT	-	SPI4_NSS, TIM1_CH2, EVENTOUT	-
-	-	-	43	L9	PE12	I/O	FT	-	SPI4_SCK, TIM1_CH3N, EVENTOUT	-
-	-	-	44	M10	PE13	I/O	FT	-	SPI4_MISO, TIM1_CH3, EVENTOUT	-

Table 8. STM32F401xD/xE pin definitions (continued)

Pin Number					Pin name (function after reset) <sup>(1)</sup>	Pin type	I/O structure	Notes	Alternate functions	Additional functions
UQFN48	WLCSP49	LQFP64	LQFP100	UFBGA100						
-	-	-	45	M11	PE14	I/O	FT	-	SPI4_MOSI, TIM1_CH4, EVENTOUT	-
-	-	-	46	M12	PE15	I/O	FT	-	TIM1_BKIN, EVENTOUT	-
21	E3	29	47	L10	PB10	I/O	FT	-	SPI2_SCK/I2S2_CK, I2C2_SCL, TIM2_CH3, EVENTOUT	-
-	-	-	-	K9	PB11	I/O	FT	-	EVENTOUT	-
22	G2	30	48	L11	VCAP1	S	-	-	-	-
23	D3	31	49	F12	VSS	S	-	-	-	-
24	F2	32	50	G12	VDD	S	-	-	-	-
25	E2	33	51	L12	PB12	I/O	FT	-	SPI2_NSS/I2S2_WS, I2C2_SMBA, TIM1_BKIN, EVENTOUT	-
26	G1	34	52	K12	PB13	I/O	FT	-	SPI2_SCK/I2S2_CK, TIM1_CH1N, EVENTOUT	-
27	F1	35	53	K11	PB14	I/O	FT	-	SPI2_MISO, I2S2ext_SD, TIM1_CH2N, EVENTOUT	-
28	E1	36	54	K10	PB15	I/O	FT	-	SPI2_MOSI/I2S2_SD, TIM1_CH3N, EVENTOUT	RTC_REFIN
-	-	-	55	-	PD8	I/O	FT	-	EVENTOUT	-
-	-	-	56	K8	PD9	I/O	FT	-	EVENTOUT	-
-	-	-	57	J12	PD10	I/O	FT	-	EVENTOUT	-
-	-	-	58	J11	PD11	I/O	FT	-	EVENTOUT	-
-	-	-	59	J10	PD12	I/O	FT	-	TIM4_CH1, EVENTOUT	-
-	-	-	60	H12	PD13	I/O	FT	-	TIM4_CH2, EVENTOUT	-
-	-	-	61	H11	PD14	I/O	FT	-	TIM4_CH3, EVENTOUT	-
-	-	-	62	H10	PD15	I/O	FT	-	TIM4_CH4, EVENTOUT	-
-	-	37	63	E12	PC6	I/O	FT	-	I2S2_MCK, USART6_TX, TIM3_CH1, SDIO_D6, EVENTOUT	-
-	-	38	64	E11	PC7	I/O	FT	-	I2S3_MCK, USART6_RX, TIM3_CH2, SDIO_D7, EVENTOUT	-

Table 8. STM32F401xD/xE pin definitions (continued)

Pin Number					Pin name (function after reset) <sup>(1)</sup>	Pin type	I/O structure	Notes	Alternate functions	Additional functions
UQFN48	WLCSP49	LQFP64	LQFP100	UFBGA100						
-	-	39	65	E10	PC8	I/O	FT	-	USART6_CK, TIM3_CH3, SDIO_D0, EVENTOUT	-
-	-	40	66	D12	PC9	I/O	FT	-	I2S_CKIN, I2C3_SDA, TIM3_CH4, SDIO_D1, MCO_2, EVENTOUT	-
29	D1	41	67	D11	PA8	I/O	FT	-	I2C3_SCL, USART1_CK, TIM1_CH1, OTG_FS_SOF, MCO_1, EVENTOUT	-
30	D2	42	68	D10	PA9	I/O	FT	-	I2C3_SMBA, USART1_TX, TIM1_CH2, EVENTOUT	OTG_FS_VBUS
31	C2	43	69	C12	PA10	I/O	FT	-	USART1_RX, TIM1_CH3, OTG_FS_ID, EVENTOUT	-
32	C1	44	70	B12	PA11	I/O	FT	-	USART1_CTS, USART6_TX, TIM1_CH4, OTG_FS_DM, EVENTOUT	-
33	C3	45	71	A12	PA12	I/O	FT	-	USART1_RTS, USART6_RX, TIM1_ETR, OTG_FS_DP, EVENTOUT	-
34	B3	46	72	A11	PA13 (JTMS-SWDIO)	I/O	FT	-	JTMS-SWDIO, EVENTOUT	-
-	-	-	73	C11	VCAP2	S	-	-	-	-
35	B1	47	74	F11	VSS	S	-	-	-	-
36	-	48	75	G11	VDD	S	-	-	-	-
-	B2	-	-	-	VDD	S	-	-	-	-
37	A1	49	76	A10	PA14 (JTCK-SWCLK)	I/O	FT	-	JTCK-SWCLK, EVENTOUT	-
38	A2	50	77	A9	PA15 (JTDI)	I/O	FT	-	JTDI, SPI1_NSS, SPI3_NSS/I2S3_WS, TIM2_CH1/TIM2_ETR, JTDI, EVENTOUT	-
-	-	51	78	B11	PC10	I/O	FT	-	SPI3_SCK/I2S3_CK, SDIO_D2, EVENTOUT	-
-	-	52	79	C10	PC11	I/O	FT	-	I2S3ext_SD, SPI3_MISO, SDIO_D3, EVENTOUT	-
-	-	53	80	B10	PC12	I/O	FT	-	SPI3_MOSI/I2S3_SD, SDIO_CK, EVENTOUT	-
-	-	-	81	C9	PD0	I/O	FT	-	EVENTOUT	-



Table 8. STM32F401xD/xE pin definitions (continued)

Pin Number					Pin name (function after reset) <sup>(1)</sup>	Pin type	I/O structure	Notes	Alternate functions	Additional functions
UQFN48	WLCSP49	LQFP64	LQFP100	UFBGA100						
-	-	-	82	B9	PD1	I/O	FT	-	EVENTOUT	-
-	-	54	83	C8	PD2	I/O	FT	-	TIM3_ETR, SDIO_CMD, EVENTOUT	-
-	-	-	84	B8	PD3	I/O	FT	-	SPI2_SCK/I2S2_CK, USART2_CTS, EVENTOUT	-
-	-	-	85	B7	PD4	I/O	FT	-	USART2_RTS, EVENTOUT	-
-	-	-	86	A6	PD5	I/O	FT	-	USART2_TX, EVENTOUT	-
-	-	-	87	B6	PD6	I/O	FT	-	SPI3_MOSI/I2S3_SD, USART2_RX, EVENTOUT	-
-	-	-	88	A5	PD7	I/O	FT	-	USART2_CK, EVENTOUT	-
39	A3	55	89	A8	PB3 (JTDO-SWO)	I/O	FT	-	JTDO-SWO, SPI1_SCK, SPI3_SCK/I2S3_CK, I2C2_SDA, TIM2_CH2, EVENTOUT	-
40	A4	56	90	A7	PB4 (NJTRST)	I/O	FT	-	NJTRST, SPI1_MISO, SPI3_MISO, I2S3ext_SD, I2C3_SDA, TIM3_CH1, EVENTOUT	-
41	B4	57	91	C5	PB5	I/O	FT	-	SPI1_MOSI, SPI3_MOSI/I2S3_SD, I2C1_SMBA, TIM3_CH2, EVENTOUT	-
42	C4	58	92	B5	PB6	I/O	FT	-	I2C1_SCL, USART1_TX, TIM4_CH1, EVENTOUT	-
43	D4	59	93	B4	PB7	I/O	FT	-	I2C1_SDA, USART1_RX, TIM4_CH2, EVENTOUT	-
44	A5	60	94	A4	BOOT0	I	B	-	-	V <sub>PP</sub>
45	B5	61	95	A3	PB8	I/O	FT	-	I2C1_SCL, TIM4_CH3, TIM10_CH1, SDIO_D4, EVENTOUT	-
46	C5	62	96	B3	PB9	I/O	FT	-	SPI2_NSS/I2S2_WS, I2C1_SDA, TIM4_CH4, TIM11_CH1, SDIO_D5, EVENTOUT	-
-	-	-	97	C3	PE0	I/O	FT	-	TIM4_ETR, EVENTOUT	-
-	-	-	98	A2	PE1	I/O	FT	-	EVENTOUT	-

Table 8. STM32F401xD/xE pin definitions (continued)

Pin Number					Pin name (function after reset) <sup>(1)</sup>	Pin type	I/O structure	Notes	Alternate functions	Additional functions
UQFN48	WLCSP49	LQFP64	LQFP100	UFBGA100						
47	A6	63	99	-	VSS	S	-	-	-	-
-	B6	-	-	H3	PDR_ON	I	FT	-	-	-
48	A7	64	100	-	VDD	S	-	-	-	-

- Function availability depends on the chosen device.
- PC13, PC14 and PC15 are supplied through the power switch. Since the switch only sinks a limited amount of current (3 mA), the use of GPIOs PC13 to PC15 in output mode is limited:
  - The speed should not exceed 2 MHz with a maximum load of 30 pF.
  - These I/Os must not be used as a current source (e.g. to drive an LED).
- Main function after the first backup domain power-up. Later on, it depends on the contents of the RTC registers even after reset (because these registers are not reset by the main reset). For details on how to manage these I/Os, refer to the RTC register description sections in the STM32F401xx reference manual.
- FT = 5 V tolerant except when in analog mode or oscillator mode (for PC14, PC15, PH0 and PH1).
- If the device is delivered in an UFBGA100 and the BYPASS\_REG pin is set to VDD (Regulator off/internal reset ON mode), then PA0 is used as an internal Reset (active low)



Table 9. Alternate function mapping

Port	AF00	AF01	AF02	AF03	AF04	AF05	AF06	AF07	AF08	AF09	AF10	AF11	AF12	AF13	AF14	AF15
	SYS_AF	TIM1/TIM2	TIM3/ TIM4/ TIM5	TIM9/ TIM10/ TIM11	I2C1/I2C2/ I2C3	SPI1/SPI2/ I2S2/SPI3/ I2S3/SPI4	SPI2/I2S2/ SPI3/ I2S3	SPI3/I2S3/ USART1/ USART2	USART6	I2C2/ I2C3	OTG1_FS		SDIO			
PA0	-	TIM2_CH1/ TIM2_ETR	TIM5_CH1	-	-	-	-	USART2_ CTS	-	-	-	-	-	-	-	EVENT OUT
PA1	-	TIM2_CH2	TIM5_CH2	-	-	-	-	USART2_ RTS	-	-	-	-	-	-	-	EVENT OUT
PA2	-	TIM2_CH3	TIM5_CH3	TIM9_CH1	-	-	-	USART2_ TX	-	-	-	-	-	-	-	EVENT OUT
PA3	-	TIM2_CH4	TIM5_CH4	TIM9_CH2	-	-	-	USART2_ RX	-	-	-	-	-	-	-	EVENT OUT
PA4	-	-	-	-	-	SPI1_NSS	SPI3_NSS/ I2S3_WS	USART2_ CK	-	-	-	-	-	-	-	EVENT OUT
PA5	-	TIM2_CH1/ TIM2_ETR	-	-	-	SPI1_SCK	-	-	-	-	-	-	-	-	-	EVENT OUT
PA6	-	TIM1_BKIN	TIM3_CH1	-	-	SPI1_ MISO	-	-	-	-	-	-	-	-	-	EVENT OUT
PA7	-	TIM1_CH1N	TIM3_CH2	-	-	SPI1_ MOSI	-	-	-	-	-	-	-	-	-	EVENT OUT
PA8	MCO_1	TIM1_CH1	-	-	I2C3_SCL	-	-	USART1_ CK	-	-	OTG_FS_ SOF	-	-	-	-	EVENT OUT
PA9	-	TIM1_CH2	-	-	I2C3_ SMBA	-	-	USART1_ TX	-	-	OTG_FS_ VBUS	-	-	-	-	EVENT OUT
PA10	-	TIM1_CH3	-	-	-	-	-	USART1_ RX	-	-	OTG_FS_I D	-	-	-	-	EVENT OUT
PA11	-	TIM1_CH4	-	-	-	-	-	USART1_ CTS	USART6_ TX	-	OTG_FS_ DM	-	-	-	-	EVENT OUT
PA12	-	TIM1_ETR	-	-	-	-	-	USART1_ RTS	USART6_ RX	-	OTG_FS_ DP	-	-	-	-	EVENT OUT
PA13	JTMS_ SWDIO	-	-	-	-	-	-	-	-	-	-	-	-	-	-	EVENT OUT
PA14	JTCK_ SWCLK	-	-	-	-	-	-	-	-	-	-	-	-	-	-	EVENT OUT
PA15	JTDI	TIM2_CH1/ TIM2_ETR	-	-	-	SPI1_NSS	SPI3_NSS/ I2S3_WS	-	-	-	-	-	-	-	-	EVENT OUT

Port A



**Table 9. Alternate function mapping (continued)**

Port	AF00	AF01	AF02	AF03	AF04	AF05	AF06	AF07	AF08	AF09	AF10	AF11	AF12	AF13	AF14	AF15	
	SYS_AF	TIM1/TIM2	TIM3/ TIM4/ TIM5	TIM9/ TIM10/ TIM11	I2C1/I2C2/ I2C3	SPI1/SPI2/ I2S2/SPI3/ I2S3/SPI4	SPI2/I2S2/ SPI3/ I2S3	SPI3/I2S3/ USART1/ USART2	USART6	I2C2/ I2C3	OTG1_FS		SDIO				
Port B	PB0	-	TIM1_CH2N	TIM3_CH3	-	-	-	-	-	-	-	-	-	-	-	EVENT OUT	
	PB1	-	TIM1_CH3N	TIM3_CH4	-	-	-	-	-	-	-	-	-	-	-	EVENT OUT	
	PB2	-	-	-	-	-	-	-	-	-	-	-	-	-	-	EVENT OUT	
	PB3	JTDO-SWO	TIM2_CH2	-	-	-	SPI1_SCK	SPI3_SCK/ I2S3_CK	-	-	I2C2_SDA	-	-	-	-	-	EVENT OUT
	PB4	JTRST	-	TIM3_CH1	-	-	SPI1_MISO	SPI3_MISO	I2S3ext_S D	-	I2C3_SDA	-	-	-	-	-	EVENT OUT
	PB5	-	-	TIM3_CH2	-	I2C1_SMBA	SPI1_MOSI	SPI3_MOSI/ I2S3_SD	-	-	-	-	-	-	-	-	EVENT OUT
	PB6	-	-	TIM4_CH1	-	I2C1_SCL	-	-	USART1_TX	-	-	-	-	-	-	-	EVENT OUT
	PB7	-	-	TIM4_CH2	-	I2C1_SDA	-	-	USART1_RX	-	-	-	-	-	-	-	EVENT OUT
	PB8	-	-	TIM4_CH3	TIM10_CH1	I2C1_SCL	-	-	-	-	-	-	-	SDIO_D4	-	-	EVENT OUT
	PB9	-	-	TIM4_CH4	TIM11_CH1	I2C1_SDA	SPI2_NSS/ 2S2_WS	-	-	-	-	-	-	SDIO_D5	-	-	EVENT OUT
	PB10	-	TIM2_CH3	-	-	I2C2_SCL	SPI2_SCK/ 2S2_CK	-	-	-	-	-	-	-	-	-	EVENT OUT
	PB12	-	TIM1_BKIN	-	-	I2C2_SMBA	SPI2_NSS/ 2S2_WS	-	-	-	-	-	-	-	-	-	EVENT OUT
	PB13	-	TIM1_CH1N	-	-	-	SPI2_SCK/ 2S2_CK	-	-	-	-	-	-	-	-	-	EVENT OUT
	PB14	-	TIM1_CH2N	-	-	-	SPI2_MISO	I2S2ext_SD	-	-	-	-	-	-	-	-	EVENT OUT
	PB15	RTC_REFN	TIM1_CH3N	-	-	-	SPI2_MOSI/ I2S2_SD	-	-	-	-	-	-	-	-	-	EVENT OUT



Table 9. Alternate function mapping (continued)

Port	AF00	AF01	AF02	AF03	AF04	AF05	AF06	AF07	AF08	AF09	AF10	AF11	AF12	AF13	AF14	AF15	
	SYS_AF	TIM1/TIM2	TIM3/ TIM4/ TIM5	TIM9/ TIM10/ TIM11	I2C1/I2C2/ I2C3	SPI1/SPI2/ I2S2/SPI3/ I2S3/SPI4	SPI2/I2S2/ SPI3/ I2S3	SPI3/I2S3/ USART1/ USART2	USART6	I2C2/ I2C3	OTG1_FS		SDIO				
Port C	PC0	-	-	-	-	-	-	-	-	-	-	-	-	-	-	EVENT OUT	
	PC1	-	-	-	-	-	-	-	-	-	-	-	-	-	-	EVENT OUT	
	PC2	-	-	-	-	-	SPI2_ MISO	I2S2ext_SD	-	-	-	-	-	-	-	EVENT OUT	
	PC3	-	-	-	-	-	SPI2_MOSI /I2S2_SD	-	-	-	-	-	-	-	-	EVENT OUT	
	PC4	-	-	-	-	-	-	-	-	-	-	-	-	-	-	EVENT OUT	
	PC5	-	-	-	-	-	-	-	-	-	-	-	-	-	-	EVENT OUT	
	PC6	-	-	TIM3_CH1	-	-	I2S2_MCK	-	-	USART6_ TX	-	-	-	SDIO_ D6	-	-	EVENT OUT
	PC7	-	-	TIM3_CH2	-	-	-	I2S3_MCK	-	USART6_ RX	-	-	-	SDIO_ D7	-	-	EVENT OUT
	PC8	-	-	TIM3_CH3	-	-	-	-	-	USART6_ CK	-	-	-	SDIO_ D0	-	-	EVENT OUT
	PC9	MCO_2	-	TIM3_CH4	-	I2C3_SDA	I2S_CKIN	-	-	-	-	-	-	SDIO_ D1	-	-	EVENT OUT
	PC10	-	-	-	-	-	-	SPI3_SCK/ I2S3_CK	-	-	-	-	-	SDIO_ D2	-	-	EVENT OUT
	PC11	-	-	-	-	-	I2S3ext_ SD	SPI3_MISO	-	-	-	-	-	SDIO_ D3	-	-	EVENT OUT
	PC12	-	-	-	-	-	-	SPI3_MOSI/ I2S3_SD	-	-	-	-	-	SDIO_ CK	-	-	EVENT OUT
	PC13	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	EVENT OUT
	PC14	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	EVENT OUT
PC15	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	EVENT OUT	



**Table 9. Alternate function mapping (continued)**

Port	AF00	AF01	AF02	AF03	AF04	AF05	AF06	AF07	AF08	AF09	AF10	AF11	AF12	AF13	AF14	AF15
	SYS_AF	TIM1/TIM2	TIM3/ TIM4/ TIM5	TIM9/ TIM10/ TIM11	I2C1/I2C2/ I2C3	SPI1/SPI2/ I2S2/SPI3/ I2S3/SPI4	SPI2/I2S2/ SPI3/ I2S3	SPI3/I2S3/ USART1/ USART2	USART6	I2C2/ I2C3	OTG1_FS		SDIO			
Port D	PD0	-	-	-	-	-	-	-	-	-	-	-	-	-	-	EVENT OUT
	PD1	-	-	-	-	-	-	-	-	-	-	-	-	-	-	EVENT OUT
	PD2	-	-	TIM3_ETR	-	-	-	-	-	-	-	-	SDIO_ CMD	-	-	EVENT OUT
	PD3	-	-	-	-	-	SPI2_SCK/ I2S2_CK	-	USART2_ CTS	-	-	-	-	-	-	EVENT OUT
	PD4	-	-	-	-	-	-	-	USART2_ RTS	-	-	-	-	-	-	EVENT OUT
	PD5	-	-	-	-	-	-	-	USART2_ TX	-	-	-	-	-	-	EVENT OUT
	PD6	-	-	-	-	-	SPI3_MOSI/ I2S3_SD	-	USART2_ RX	-	-	-	-	-	-	EVENT OUT
	PD7	-	-	-	-	-	-	-	USART2_ CK	-	-	-	-	-	-	EVENT OUT
	PD8	-	-	-	-	-	-	-	-	-	-	-	-	-	-	EVENT OUT
	PD9	-	-	-	-	-	-	-	-	-	-	-	-	-	-	EVENT OUT
	PD10	-	-	-	-	-	-	-	-	-	-	-	-	-	-	EVENT OUT
	PD11	-	-	-	-	-	-	-	-	-	-	-	-	-	-	EVENT OUT
	PD12	-	-	TIM4_CH1	-	-	-	-	-	-	-	-	-	-	-	EVENT OUT
	PD13	-	-	TIM4_CH2	-	-	-	-	-	-	-	-	-	-	-	EVENT OUT
	PD14	-	-	TIM4_CH3	-	-	-	-	-	-	-	-	-	-	-	EVENT OUT
PD15	-	-	TIM4_CH4	-	-	-	-	-	-	-	-	-	-	-	EVENT OUT	



Table 9. Alternate function mapping (continued)

Port	AF00	AF01	AF02	AF03	AF04	AF05	AF06	AF07	AF08	AF09	AF10	AF11	AF12	AF13	AF14	AF15
	SYS_AF	TIM1/TIM2	TIM3/ TIM4/ TIM5	TIM9/ TIM10/ TIM11	I2C1/I2C2/ I2C3	SPI1/SPI2/ I2S2/SPI3/ I2S3/SPI4	SPI2/I2S2/ SPI3/ I2S3	SPI3/I2S3/ USART1/ USART2	USART6	I2C2/ I2C3	OTG1_FS		SDIO			
Port E	PE0	-	-	TIM4_ETR	-	-	-	-	-	-	-	-	-	-	-	EVENT OUT
	PE1	-	TIM1_CH2N	-	-	-	-	-	-	-	-	-	-	-	-	EVENT OUT
	PE2	TRACECLK	-	-	-	-	SPI4_SCK	-	-	-	-	-	-	-	-	EVENT OUT
	PE3	TRACED0	-	-	-	-	-	-	-	-	-	-	-	-	-	EVENT OUT
	PE4	TRACED1	-	-	-	-	SPI4_NSS	-	-	-	-	-	-	-	-	EVENT OUT
	PE5	TRACED2	-	-	TIM9_CH1	-	SPI4_MISO	-	-	-	-	-	-	-	-	EVENT OUT
	PE6	TRACED3	-	-	TIM9_CH2	-	SPI4_MOSI	-	-	-	-	-	-	-	-	EVENT OUT
	PE7	-	TIM1_ETR	-	-	-	-	-	-	-	-	-	-	-	-	EVENT OUT
	PE8	-	TIM1_CH1N	-	-	-	-	-	-	-	-	-	-	-	-	EVENT OUT
	PE9	-	TIM1_CH1	-	-	-	-	-	-	-	-	-	-	-	-	EVENT OUT
	PE10	-	TIM1_CH2N	-	-	-	-	-	-	-	-	-	-	-	-	EVENT OUT
	PE11	-	TIM1_CH2	-	-	-	SPI4_NSS	-	-	-	-	-	-	-	-	EVENT OUT
	PE12	-	TIM1_CH3N	-	-	-	SPI4_SCK	-	-	-	-	-	-	-	-	EVENT OUT
	PE13	-	TIM1_CH3	-	-	-	SPI4_MISO	-	-	-	-	-	-	-	-	EVENT OUT
	PE14	-	TIM1_CH4	-	-	-	SPI4_MOSI	-	-	-	-	-	-	-	-	EVENT OUT
	PE15	-	TIM1_BKIN	-	-	-	-	-	-	-	-	-	-	-	-	EVENT OUT



Table 9. Alternate function mapping (continued)

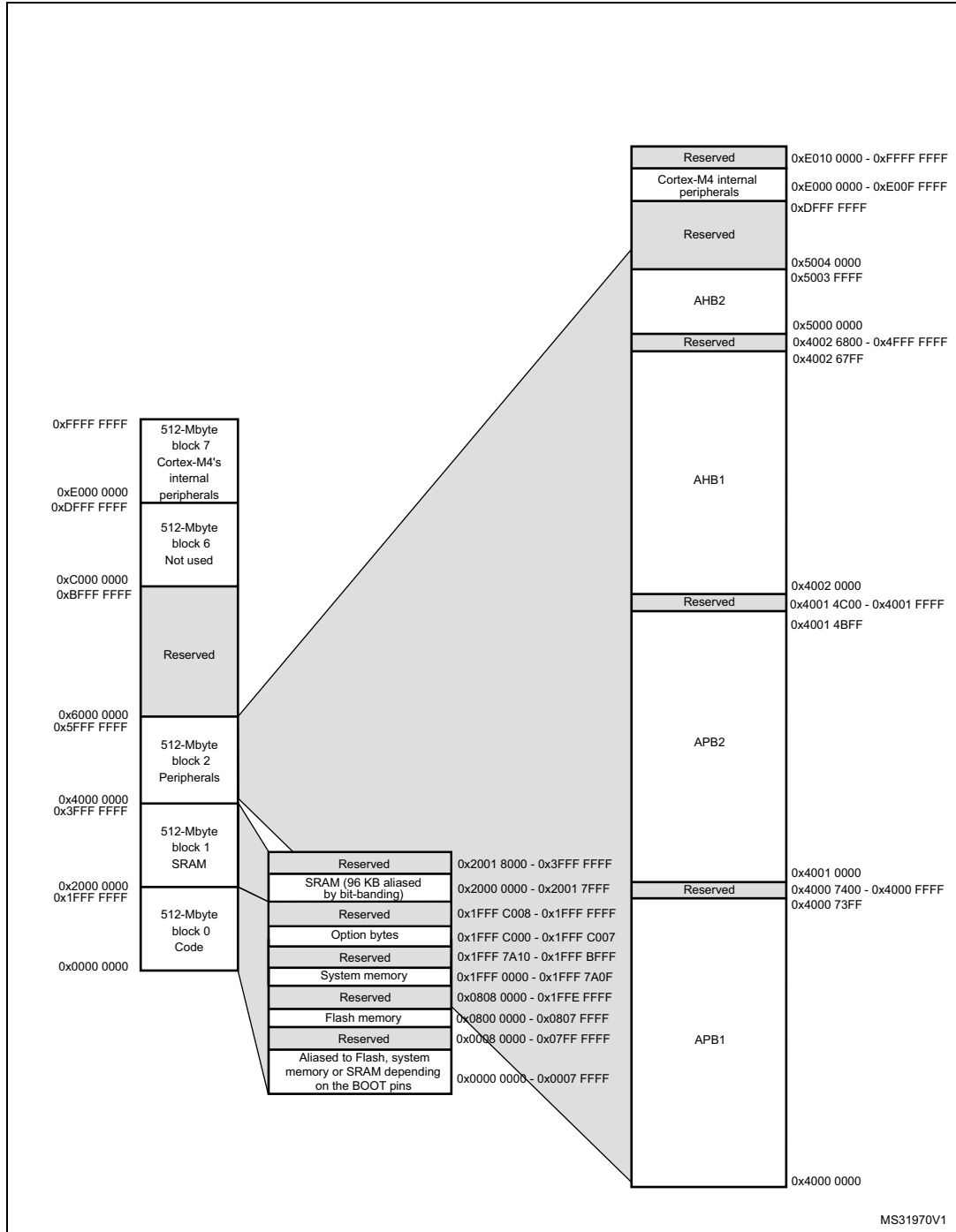
Port	AF00	AF01	AF02	AF03	AF04	AF05	AF06	AF07	AF08	AF09	AF10	AF11	AF12	AF13	AF14	AF15
	SYS_AF	TIM1/TIM2	TIM3/ TIM4/ TIM5	TIM9/ TIM10/ TIM11	I2C1/I2C2/ I2C3	SPI1/SPI2/ I2S2/SPI3/ I2S3/SPI4	SPI2/I2S2/ SPI3/ I2S3	SPI3/I2S3/ USART1/ USART2	USART6	I2C2/ I2C3	OTG1_FS		SDIO			
Port H	PH0	-	-	-	-	-	-	-	-	-	-	-	-	-	-	EVENT OUT
	PH1	-	-	-	-	-	-	-	-	-	-	-	-	-	-	EVENT OUT



# 5 Memory mapping

The memory map is shown in [Figure 15](#).

Figure 15. Memory map



MS31970V1

Table 10. STM32F401xD register boundary addresses

Bus	Boundary address	Peripheral
	0xE010 0000 - 0xFFFF FFFF	Reserved
Cortex <sup>®</sup> -M4	0xE000 0000 - 0xE00F FFFF	Cortex-M4 internal peripherals
	0x5004 0000 - 0xDFFF FFFF	Reserved
AHB2	0x5000 0000 - 0x5003 FFFF	USB OTG FS
AHB1	0x4002 6800 - 0x4FFF FFFF	Reserved
	0x4002 6400 - 0x4002 67FF	DMA2
	0x4002 6000 - 0x4002 63FF	DMA1
	0x4002 5000 - 0x4002 4FFF	Reserved
	0x4002 3C00 - 0x4002 3FFF	Flash interface register
	0x4002 3800 - 0x4002 3BFF	RCC
	0x4002 3400 - 0x4002 37FF	Reserved
	0x4002 3000 - 0x4002 33FF	CRC
	0x4002 2000 - 0x4002 2FFF	Reserved
	0x4002 1C00 - 0x4002 1FFF	GPIOH
	0x4002 1400 - 0x4002 1BFF	Reserved
	0x4002 1000 - 0x4002 13FF	GPIOE
	0x4002 0C00 - 0x4002 0FFF	GIOD
	0x4002 0800 - 0x4002 0BFF	GPIOC
	0x4002 0400 - 0x4002 07FF	GPIOB
	0x4002 0000 - 0x4002 03FF	GPIOA

**Table 10. STM32F401xD register boundary addresses (continued)**

Bus	Boundary address	Peripheral
APB2	0x4001 4C00 - 0x4001 FFFF	Reserved
	0x4001 4800 - 0x4001 4BFF	TIM11
	0x4001 4400 - 0x4001 47FF	TIM10
	0x4001 4000 - 0x4001 43FF	TIM9
	0x4001 3C00 - 0x4001 3FFF	EXTI
	0x4001 3800 - 0x4001 3BFF	SYSCFG
	0x4001 3400 - 0x4001 37FF	SPI4/I2S4
	0x4001 3000 - 0x4001 33FF	SPI1
	0x4001 2C00 - 0x4001 2FFF	SDIO
	0x4001 2400 - 0x4001 2BFF	Reserved
	0x4001 2000 - 0x4001 23FF	ADC1
	0x4001 1800 - 0x4001 1FFF	Reserved
	0x4001 1400 - 0x4001 17FF	USART6
	0x4001 1000 - 0x4001 13FF	USART1
	0x4001 0800 - 0x4001 0FFF	Reserved
	0x4001 0400 - 0x4001 07FF	TIM8
	0x4001 0000 - 0x4001 03FF	TIM1
	0x4000 7400 - 0x4000 FFFF	Reserved

Table 10. STM32F401xD register boundary addresses (continued)

Bus	Boundary address	Peripheral
APB1	0x4000 7000 - 0x4000 73FF	PWR
	0x4000 6000 - 0x4000 6FFF	Reserved
	0x4000 5C00 - 0x4000 5FFF	I2C3
	0x4000 5800 - 0x4000 5BFF	I2C2
	0x4000 5400 - 0x4000 57FF	I2C1
	0x4000 4800 - 0x4000 53FF	Reserved
	0x4000 4400 - 0x4000 47FF	USART2
	0x4000 4000 - 0x4000 43FF	I2S3ext
	0x4000 3C00 - 0x4000 3FFF	SPI3 / I2S3
	0x4000 3800 - 0x4000 3BFF	SPI2 / I2S2
	0x4000 3400 - 0x4000 37FF	I2S2ext
	0x4000 3000 - 0x4000 33FF	IWDG
	0x4000 2C00 - 0x4000 2FFF	WWDG
	0x4000 2800 - 0x4000 2BFF	RTC & BKP Registers
	0x4000 1000 - 0x4000 27FF	Reserved
	0x4000 0C00 - 0x4000 0FFF	TIM5
	0x4000 0800 - 0x4000 0BFF	TIM4
	0x4000 0400 - 0x4000 07FF	TIM3
	0x4000 0000 - 0x4000 03FF	TIM2

## 6 Electrical characteristics

### 6.1 Parameter conditions

Unless otherwise specified, all voltages are referenced to  $V_{SS}$ .

#### 6.1.1 Minimum and maximum values

Unless otherwise specified the minimum and maximum values are guaranteed in the worst conditions of ambient temperature, supply voltage and frequencies by tests in production on 100% of the devices with an ambient temperature at  $T_A = 25\text{ °C}$  and  $T_A = T_{A\text{max}}$  (given by the selected temperature range).

Data based on characterization results, design simulation and/or technology characteristics are indicated in the table footnotes and are not tested in production. Based on characterization, the minimum and maximum values refer to sample tests and represent the mean value plus or minus three times the standard deviation (mean  $\pm 3\sigma$ ).

#### 6.1.2 Typical values

Unless otherwise specified, typical data are based on  $T_A = 25\text{ °C}$ ,  $V_{DD} = 3.3\text{ V}$  (for the  $1.7\text{ V} \leq V_{DD} \leq 3.6\text{ V}$  voltage range). They are given only as design guidelines and are not tested.

Typical ADC accuracy values are determined by characterization of a batch of samples from a standard diffusion lot over the full temperature range, where 95% of the devices have an error less than or equal to the value indicated (mean  $\pm 2\sigma$ ).

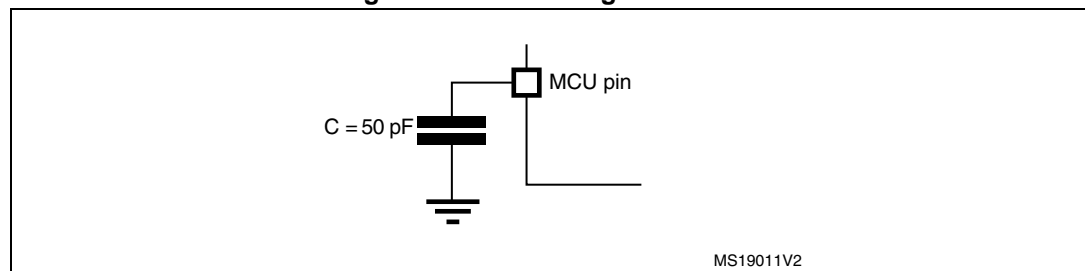
#### 6.1.3 Typical curves

Unless otherwise specified, all typical curves are given only as design guidelines and are not tested.

#### 6.1.4 Loading capacitor

The loading conditions used for pin parameter measurement are shown in [Figure 16](#).

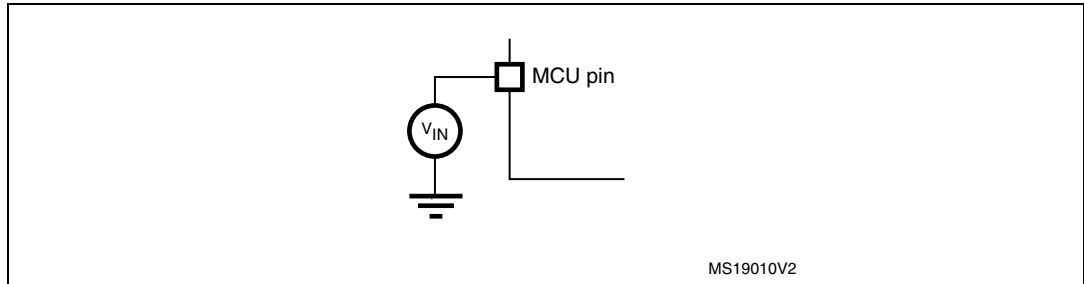
**Figure 16. Pin loading conditions**



### 6.1.5 Pin input voltage

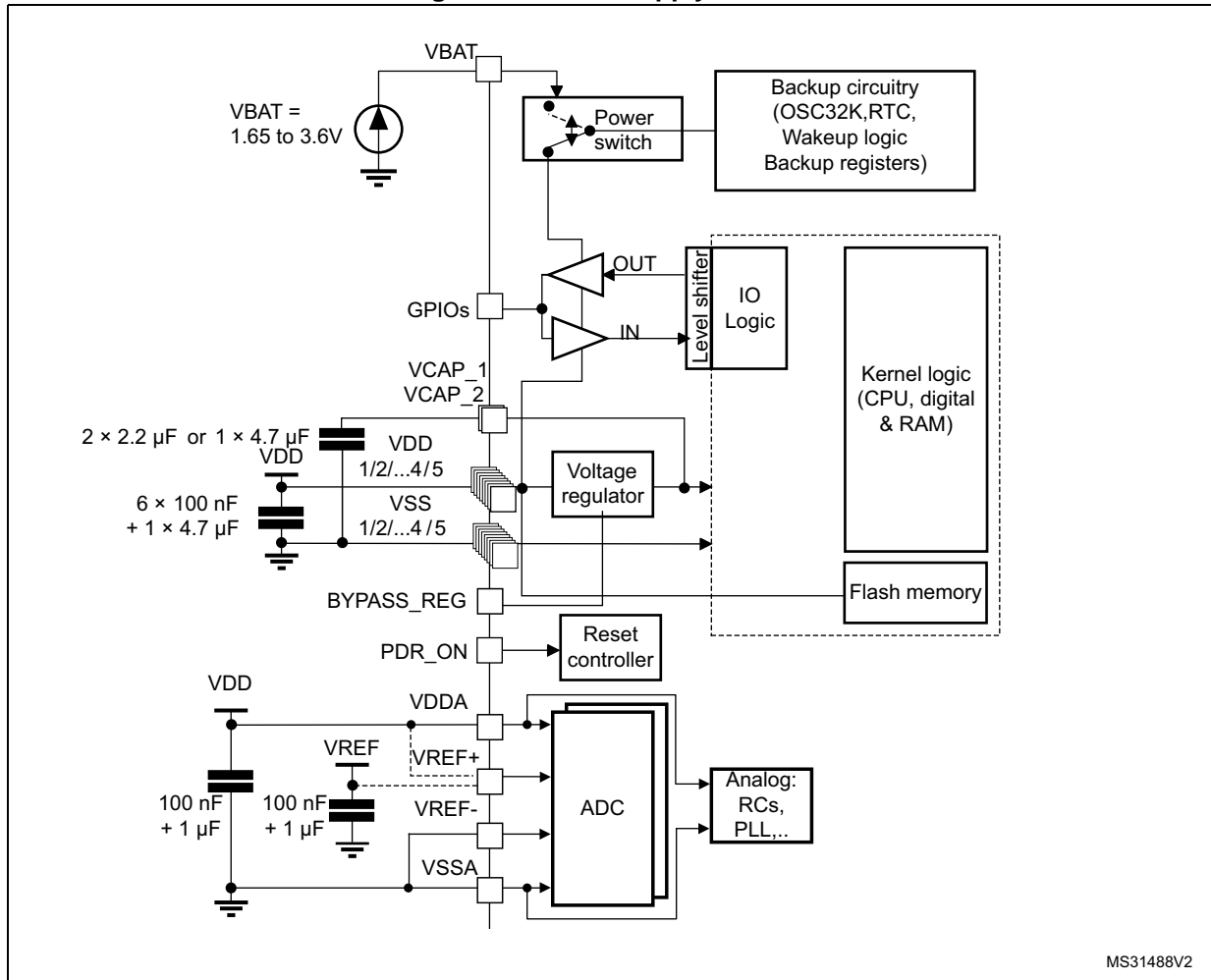
The input voltage measurement on a pin of the device is described in [Figure 17](#).

**Figure 17. Input voltage measurement**



6.1.6 Power supply scheme

Figure 18. Power supply scheme



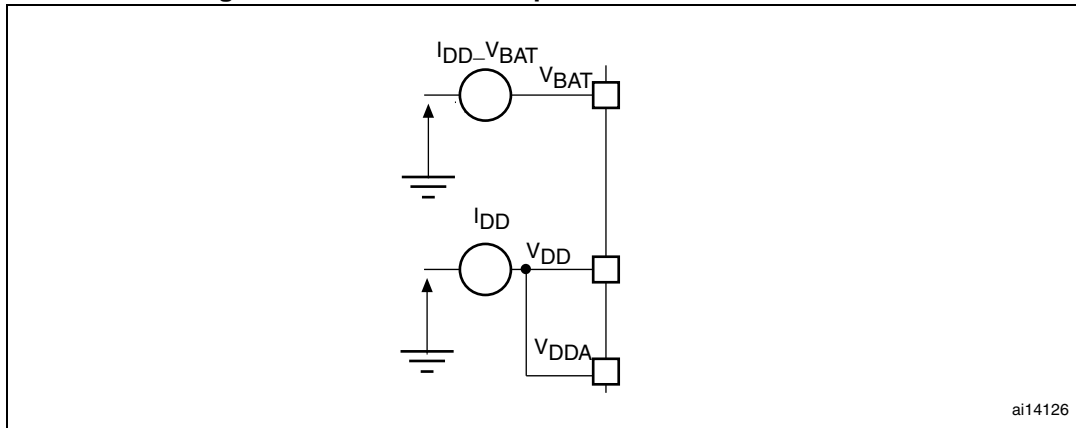
MS31488V2

1. To connect PDR\_ON pin, refer to [Section 3.14: Power supply supervisor](#).
2. The 4.7 µF ceramic capacitor must be connected to one of the V<sub>DD</sub> pin.
3. V<sub>CAP\_2</sub> pad is only available on LQFP100 and UFBGA100 packages.
4. V<sub>DDA</sub>=V<sub>DD</sub> and V<sub>SSA</sub>=V<sub>SS</sub>.

**Caution:** Each power supply pair (V<sub>DD</sub>/V<sub>SS</sub>, V<sub>DDA</sub>/V<sub>SSA</sub> ...) must be decoupled with filtering ceramic capacitors as shown above. These capacitors must be placed as close as possible to, or below, the appropriate pins on the underside of the PCB to ensure good operation of the device. It is not recommended to remove filtering capacitors to reduce PCB size or cost. This might cause incorrect operation of the device.

### 6.1.7 Current consumption measurement

Figure 19. Current consumption measurement scheme



## 6.2 Absolute maximum ratings

Stresses above the absolute maximum ratings listed in [Table 11: Voltage characteristics](#), [Table 12: Current characteristics](#), and [Table 13: Thermal characteristics](#) may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these conditions is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

Table 11. Voltage characteristics

Symbol	Ratings	Min	Max	Unit
$V_{DD}-V_{SS}$	External main supply voltage (including $V_{DDA}$ , $V_{DD}$ and $V_{BAT}$ ) <sup>(1)</sup>	-0.3	4.0	V
$V_{IN}$	Input voltage on FT pins <sup>(2)</sup>	$V_{SS}-0.3$	$V_{DD}+4.0$	
	Input voltage on any other pin	$V_{SS}-0.3$	4.0	
	Input voltage for BOOT0	$V_{SS}$	9.0	
$ \Delta V_{DDx} $	Variations between different $V_{DD}$ power pins	-	50	mV
$ V_{SSx}-V_{SS} $	Variations between all the different ground pins	-	50	
$V_{ESD(HBM)}$	Electrostatic discharge voltage (human body model)	see <a href="#">Section 6.3.14: Absolute maximum ratings (electrical sensitivity)</a>		

1. All main power ( $V_{DD}$ ,  $V_{DDA}$ ) and ground ( $V_{SS}$ ,  $V_{SSA}$ ) pins must always be connected to the external power supply, in the permitted range.
2.  $V_{IN}$  maximum value must always be respected. Refer to [Table 12](#) for the values of the maximum allowed injected current.



**Table 12. Current characteristics**

Symbol	Ratings	Max.	Unit
$\Sigma I_{VDD}$	Total current into sum of all $V_{DD\_x}$ power lines (source) <sup>(1)</sup>	160	mA
$\Sigma I_{VSS}$	Total current out of sum of all $V_{SS\_x}$ ground lines (sink) <sup>(1)</sup>	-160	
$I_{VDD}$	Maximum current into each $V_{DD\_x}$ power line (source) <sup>(1)</sup>	100	
$I_{VSS}$	Maximum current out of each $V_{SS\_x}$ ground line (sink) <sup>(1)</sup>	-100	
$I_{IO}$	Output current sunk by any I/O and control pin	25	
	Output current sourced by any I/O and control pin	-25	
$\Sigma I_{IO}$	Total output current sunk by sum of all I/O and control pins <sup>(2)</sup>	120	
	Total output current sourced by sum of all I/Os and control pins <sup>(2)</sup>	-120	
$I_{INJ(PIN)}$ <sup>(3)</sup>	Injected current on FT pins <sup>(4)</sup>	-5/+0	
	Injected current on NRST and B pins <sup>(4)</sup>		
$\Sigma I_{INJ(PIN)}$	Total injected current (sum of all I/O and control pins) <sup>(5)</sup>	±25	

1. All main power ( $V_{DD}$ ,  $V_{DDA}$ ) and ground ( $V_{SS}$ ,  $V_{SSA}$ ) pins must always be connected to the external power supply, in the permitted range.
2. This current consumption must be correctly distributed over all I/Os and control pins. The total output current must not be sunk/sourced between two consecutive power supply pins referring to high pin count LQFP packages.
3. Negative injection disturbs the analog performance of the device. See note in [Section 6.3.20: 12-bit ADC characteristics](#).
4. Positive injection is not possible on these I/Os and does not occur for input voltages lower than the specified maximum value.
5. When several inputs are submitted to a current injection, the maximum  $\Sigma I_{INJ(PIN)}$  is the absolute sum of the positive and negative injected currents (instantaneous values).

**Table 13. Thermal characteristics**

Symbol	Ratings	Value	Unit
$T_{STG}$	Storage temperature range	-65 to +150	°C
$T_J$	Maximum junction temperature	125	
$T_{LEAD}$	Maximum lead temperature during soldering (WLCSP49, LQFP64/100, UFQFPN48, UFBGA100)	see note <sup>(1)</sup>	

1. Compliant with JEDEC Std J-STD-020D (for small body, Sn-Pb or Pb assembly), the ST ECOPACK<sup>®</sup> 7191395 specification, and the European directive on Restrictions on Hazardous Substances (ROHS directive 2011/65/EU, July 2011).

## 6.3 Operating conditions

### 6.3.1 General operating conditions

Table 14. General operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f <sub>HCLK</sub>	Internal AHB clock frequency	Power Scale3: Regulator ON, VOS[1:0] bits in PWR_CR register = 0x01	0	-	60	MHz
		Power Scale2: Regulator ON, VOS[1:0] bits in PWR_CR register = 0x10	0	-	84	
f <sub>PCLK1</sub>	Internal APB1 clock frequency		0	-	42	
f <sub>PCLK2</sub>	Internal APB2 clock frequency		0	-	84	
V <sub>DD</sub>	Standard operating voltage		1.7 <sup>(1)</sup>	-	3.6	
V <sub>DDA</sub> (2)(3)	Analog operating voltage (ADC limited to 1.2 M samples)	Must be the same potential as V <sub>DD</sub> <sup>(4)</sup>	1.7 <sup>(1)</sup>	-	2.4	
	Analog operating voltage (ADC limited to 2.4 M samples)		2.4	-	3.6	
V <sub>BAT</sub>	Backup operating voltage		1.65	-	3.6	
V <sub>12</sub>	Regulator ON: 1.2 V internal voltage on V <sub>CAP_1</sub> /V <sub>CAP_2</sub> pins	VOS[1:0] bits in PWR_CR register = 0x01 Max frequency 60 MHz	1.08 <sup>(5)</sup>	1.14	1.20 <sup>(5)</sup>	V
		VOS[1:0] bits in PWR_CR register = 0x10 Max frequency 84 MHz	1.20 <sup>(5)</sup>	1.26	1.32 <sup>(5)</sup>	
V <sub>12</sub>	Regulator OFF: 1.2 V external voltage must be supplied on V <sub>CAP_1</sub> /V <sub>CAP_2</sub> pins	Max. frequency 60 MHz.	1.1	1.14	1.2	
		Max. frequency 84 MHz.	1.2	1.26	1.32	
V <sub>IN</sub>	Input voltage on RST and FT pins <sup>(6)</sup>	2 V ≤ V <sub>DD</sub> ≤ 3.6 V	-0.3	-	5.5	
		V <sub>DD</sub> ≤ 2 V	-0.3	-	5.2	
	Input voltage on BOOT0 pin		0	-	9	
P <sub>D</sub>	Maximum allowed package power dissipation for suffix 7 <sup>(7)</sup>	UFQFPN48	-	-	625	mW
		WLCSP49	-	-	392	
		LQFP64	-	-	313	
		LQFP100	-	-	465	
		UFBGA100	-	-	323	

**Table 14. General operating conditions (continued)**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
T <sub>A</sub>	Ambient temperature for 6 suffix version	Maximum power dissipation	-40	-	85	°C
		Low power dissipation <sup>(8)</sup>	-40	-	105	
	Ambient temperature for 7 suffix version	Maximum power dissipation	-40	-	105	
		Low power dissipation <sup>(8)</sup>	-40	-	125	
T <sub>J</sub>	Junction temperature range	6 suffix version	-40	-	105	
		7 suffix version	-40	-	125	

- V<sub>DD</sub>/V<sub>DDA</sub> minimum value of 1.7 V with the use of an external power supply supervisor (refer to [Section 3.14.2: Internal reset OFF](#)).
- When the ADC is used, refer to [Table 66: ADC characteristics](#).
- If V<sub>REF+</sub> pin is present, it must respect the following condition: V<sub>DDA</sub>-V<sub>REF+</sub> < 1.2 V.
- It is recommended to power V<sub>DD</sub> and V<sub>DDA</sub> from the same source. A maximum difference of 300 mV between V<sub>DD</sub> and V<sub>DDA</sub> can be tolerated during power-up and power-down operation.
- Guaranteed by test in production
- To sustain a voltage higher than V<sub>DD</sub>+0.3, the internal Pull-up and Pull-Down resistors must be disabled
- If T<sub>A</sub> is lower, higher P<sub>D</sub> values are allowed as long as T<sub>J</sub> does not exceed T<sub>Jmax</sub>.
- In low power dissipation state, T<sub>A</sub> can be extended to this range as long as T<sub>J</sub> does not exceed T<sub>Jmax</sub>.

**Table 15. Features depending on the operating power supply range**

Operating power supply range	ADC operation	Maximum Flash memory access frequency with no wait states (f <sub>Flashmax</sub> )	Maximum Flash memory access frequency with wait states <sup>(1)(2)</sup>	I/O operation	Clock output frequency on I/O pins <sup>(3)</sup>	Possible Flash memory operations
V <sub>DD</sub> = 1.7 to 2.1 V <sup>(4)</sup>	Conversion time up to 1.2 Msps	20 MHz <sup>(5)</sup>	84 MHz with 4 wait states	- No I/O compensation	up to 30 MHz	8-bit erase and program operations only
V <sub>DD</sub> = 2.1 to 2.4 V	Conversion time up to 1.2 Msps	22 MHz	84 MHz with 3 wait states	- No I/O compensation	up to 30 MHz	16-bit erase and program operations
V <sub>DD</sub> = 2.4 to 2.7 V	Conversion time up to 2.4 Msps	24 MHz	84 MHz with 3 wait states	- I/O compensation works	up to 48 MHz	16-bit erase and program operations
V <sub>DD</sub> = 2.7 to 3.6 V <sup>(6)</sup>	Conversion time up to 2.4 Msps	30 MHz	84 MHz with 2 wait states	- I/O compensation works	- up to 84 MHz when V <sub>DD</sub> = 3.0 to 3.6 V - up to 48 MHz when V <sub>DD</sub> = 2.7 to 3.0 V	32-bit erase and program operations

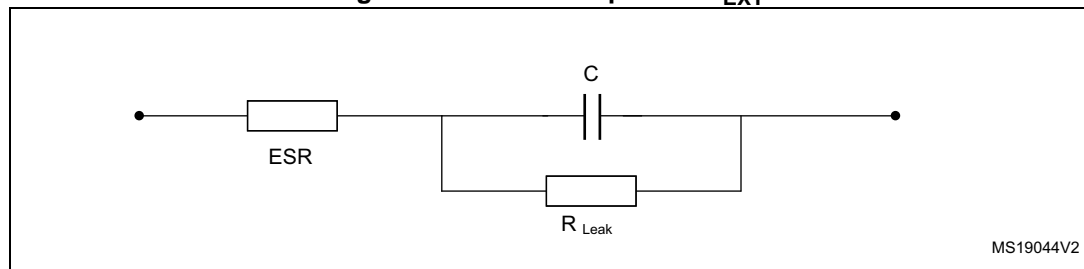
1. Applicable only when the code is executed from Flash memory. When the code is executed from RAM, no wait state is required.
2. Thanks to the ART accelerator and the 128-bit Flash memory, the number of wait states given here does not impact the execution speed from Flash memory since the ART accelerator allows to achieve a performance equivalent to 0 wait state program execution.
3. Refer to for frequencies vs. external load.
4.  $V_{DD}/V_{DDA}$  minimum value of 1.7 V, with the use of an external power supply supervisor (refer to [Section 3.14.2: Internal reset OFF](#)).
5. Prefetch is not available. Refer to AN3430 application note for details on how to adjust performance and power.
6. The voltage range for the USB full speed embedded PHY can drop down to 2.7 V. However the electrical characteristics of D- and D+ pins will be degraded between 2.7 and 3 V.

### 6.3.2 VCAP1/VCAP2 external capacitors

Stabilization for the main regulator is achieved by connecting external capacitor  $C_{EXT}$  to the VCAP1 and VCAP2 pin. For packages supporting only 1 VCAP pin, the 2 CEXT capacitors are replaced by a single capacitor.

$C_{EXT}$  is specified in [Table 16](#).

Figure 20. External capacitor  $C_{EXT}$



1. Legend: ESR is the equivalent series resistance.

Table 16. VCAP1/VCAP2 operating conditions<sup>(1)</sup>

Symbol	Parameter	Conditions
C <sub>EXT</sub>	Capacitance of external capacitor with available VCAP1 and VCAP2 pins	2.2 μF
ESR	ESR of external capacitor with available VCAP1 and VCAP2 pins	< 2 Ω
C <sub>EXT</sub>	Capacitance of external capacitor with a single VCAP pin available	4.7 μF
ESR	ESR of external capacitor with a single VCAP pin available	< 1 Ω

1. When bypassing the voltage regulator, the two 2.2 μF  $V_{CAP}$  capacitors are not required and should be replaced by two 100 nF decoupling capacitors.

### 6.3.3 Operating conditions at power-up/power-down (regulator ON)

Subject to general operating conditions for  $T_A$ .

**Table 17. Operating conditions at power-up / power-down (regulator ON)**

Symbol	Parameter	Min	Max	Unit
$t_{VDD}$	$V_{DD}$ rise time rate	20	$\infty$	$\mu\text{s/V}$
	$V_{DD}$ fall time rate	20	$\infty$	

### 6.3.4 Operating conditions at power-up / power-down (regulator OFF)

Subject to general operating conditions for  $T_A$ .

**Table 18. Operating conditions at power-up / power-down (regulator OFF)<sup>(1)</sup>**

Symbol	Parameter	Conditions	Min	Max	Unit
$t_{VDD}$	$V_{DD}$ rise time rate	Power-up	20	$\infty$	$\mu\text{s/V}$
	$V_{DD}$ fall time rate	Power-down	20	$\infty$	
$t_{VCAP}$	$V_{CAP\_1}$ and $V_{CAP\_2}$ rise time rate	Power-up	20	$\infty$	
	$V_{CAP\_1}$ and $V_{CAP\_2}$ fall time rate	Power-down	20	$\infty$	

1. To reset the internal logic at power-down, a reset must be applied on pin PA0 when  $V_{DD}$  reach below 1.08 V.

*Note:* This feature is only available for UFBGA100 package.

### 6.3.5 Embedded reset and power control block characteristics

The parameters given in [Table 19](#) are derived from tests performed under ambient temperature and  $V_{DD}$  supply voltage @ 3.3V.

**Table 19. Embedded reset and power control block characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{PVD}$	Programmable voltage detector level selection	PLS[2:0]=000 (rising edge)	2.09	2.14	2.19	V
		PLS[2:0]=000 (falling edge)	1.98	2.04	2.08	
		PLS[2:0]=001 (rising edge)	2.23	2.30	2.37	
		PLS[2:0]=001 (falling edge)	2.13	2.19	2.25	
		PLS[2:0]=010 (rising edge)	2.39	2.45	2.51	
		PLS[2:0]=010 (falling edge)	2.29	2.35	2.39	
		PLS[2:0]=011 (rising edge)	2.54	2.60	2.65	
		PLS[2:0]=011 (falling edge)	2.44	2.51	2.56	
		PLS[2:0]=100 (rising edge)	2.70	2.76	2.82	
		PLS[2:0]=100 (falling edge)	2.59	2.66	2.71	
		PLS[2:0]=101 (rising edge)	2.86	2.93	2.99	
		PLS[2:0]=101 (falling edge)	2.65	2.84	3.02	
		PLS[2:0]=110 (rising edge)	2.96	3.03	3.10	
		PLS[2:0]=110 (falling edge)	2.85	2.93	2.99	
		PLS[2:0]=111 (rising edge)	3.07	3.14	3.21	
PLS[2:0]=111 (falling edge)	2.95	3.03	3.09			
$V_{PVDhyst}^{(2)}$	PVD hysteresis		-	100	-	mV
$V_{POR/PDR}$	Power-on/power-down reset threshold	Falling edge	1.60 <sup>(1)</sup>	1.68	1.76	V
		Rising edge	1.64	1.72	1.80	
$V_{PDRhyst}^{(2)}$	PDR hysteresis		-	40	-	mV
$V_{BOR1}$	Brownout level 1 threshold	Falling edge	2.13	2.19	2.24	V
		Rising edge	2.23	2.29	2.33	
$V_{BOR2}$	Brownout level 2 threshold	Falling edge	2.44	2.50	2.56	
		Rising edge	2.53	2.59	2.63	
$V_{BOR3}$	Brownout level 3 threshold	Falling edge	2.75	2.83	2.88	
		Rising edge	2.85	2.92	2.97	
$V_{BORhyst}^{(2)}$	BOR hysteresis		-	100	-	mV
$T_{RSTTEMPO}^{(2)(3)}$	POR reset timing		0.5	1.5	3.0	ms

Table 19. Embedded reset and power control block characteristics (continued)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{RUSH}^{(2)}$	InRush current on voltage regulator power-on (POR or wakeup from Standby)		-	160	200	mA
$E_{RUSH}^{(2)}$	InRush energy on voltage regulator power-on (POR or wakeup from Standby)	$V_{DD} = 1.7\text{ V}$ , $T_A = 105\text{ °C}$ , $I_{RUSH} = 171\text{ mA}$ for $31\text{ }\mu\text{s}$	-	-	5.4	$\mu\text{C}$

1. The product behavior is guaranteed by design down to the minimum  $V_{POR/PDR}$  value.
2. Guaranteed by design, not tested in production.
3. The reset timing is measured from the power-on (POR reset or wakeup from  $V_{BAT}$ ) to the instant when first instruction is fetched by the user application code.

### 6.3.6 Supply current characteristics

The current consumption is a function of several parameters and factors such as the operating voltage, ambient temperature, I/O pin loading, device software configuration, operating frequencies, I/O pin switching rate, program location in memory and executed binary code.

The current consumption is measured as described in [Figure 19: Current consumption measurement scheme](#).

All the run-mode current consumption measurements given in this section are performed with a reduced code that gives a consumption equivalent to CoreMark code.

#### Typical and maximum current consumption

The MCU is placed under the following conditions:

- All I/O pins are in input mode with a static value at VDD or VSS (no load).
- All peripherals are disabled except if it is explicitly mentioned.
- The Flash memory access time is adjusted to both  $f_{HCLK}$  frequency and VDD ranges (refer to [Table 15: Features depending on the operating power supply range](#)).
- The voltage scaling is adjusted to  $f_{HCLK}$  frequency as follows:
  - Scale 3 for  $f_{HCLK} \leq 60\text{ MHz}$
  - Scale 2 for  $60\text{ MHz} < f_{HCLK} \leq 84\text{ MHz}$
- The system clock is HCLK,  $f_{PCLK1} = f_{HCLK}/2$ , and  $f_{PCLK2} = f_{HCLK}$ .
- External clock is 4 MHz and PLL is on
- The maximum values are obtained for  $V_{DD} = 3.6\text{ V}$  and a maximum ambient temperature ( $T_A$ ), and the typical values for  $T_A = 25\text{ °C}$  and  $V_{DD} = 3.3\text{ V}$  unless otherwise specified.

**Table 20. Typical and maximum current consumption, code with data processing (ART accelerator disabled) running from SRAM - V<sub>DD</sub> = 1.7 V**

Symbol	Parameter	Conditions	f <sub>HCLK</sub> (MHz)	Typ	Max <sup>(1)</sup>			Unit
				T <sub>A</sub> =25 °C	T <sub>A</sub> =25 °C	T <sub>A</sub> =85 °C	T <sub>A</sub> =105 °C	
I <sub>DD</sub>	Supply current in Run mode	External clock, all peripherals enabled <sup>(2)(3)</sup>	84	21.8	23.1	24.1	25.3 <sup>(4)</sup>	mA
			60	15.8	16.5	17.5	18.7	
			40	11.4	11.9	12.9	13.9	
			20	6.0	6.3	7.3	8.3	
		External clock, all peripherals disabled <sup>(3)</sup>	84	12.7	13.5	14.5	16.3 <sup>(4)</sup>	
			60	9.2	10.5	11.5	12.8	
			40	6.7	7.1	8.1	9.1	
			20	3.6	3.8	4.8	5.8	

1. Guaranteed by characterization, not tested in production unless otherwise specified
2. When analog peripheral blocks such as ADC, HSE, LSE, HSI, or LSI are ON, an additional power consumption has to be considered.
3. When the ADC is ON (ADON bit set in the ADC\_CR2 register), add an additional power consumption of 1.6 mA for the analog part.
4. Tested in production.

**Table 21. Typical and maximum current consumption, code with data processing (ART accelerator disabled) running from SRAM**

Symbol	Parameter	Conditions	f <sub>HCLK</sub> (MHz)	Typ	Max <sup>(1)</sup>			Unit
					T <sub>A</sub> =25 °C	T <sub>A</sub> =85 °C	T <sub>A</sub> =105 °C	
I <sub>DD</sub>	Supply current in Run mode	External clock, all peripherals enabled <sup>(2)(3)</sup>	84	22.0	23.1	24.1	25.3	mA
			60	16.0	16.9	17.9	19.8	
			40	11.6	12.1	13.1	14.1	
			20	6.2	6.5	7.5	8.5	
		External clock, all peripherals disabled <sup>(3)</sup>	84	12.9	14.0	15.0	16.3	
			60	9.5	10.5	11.5	12.8	
			40	6.9	7.3	8.3	9.3	
			20	3.8	4.0	5.0	6.0	

1. Guaranteed by characterization, not tested in production unless otherwise specified
2. When analog peripheral blocks such as ADC, HSE, LSE, HSI, or LSI are ON, an additional power consumption has to be considered.
3. When the ADC is ON (ADON bit set in the ADC\_CR2 register), add an additional power consumption of 1.6 mA for the analog part.



**Table 22. Typical and maximum current consumption in run mode, code with data processing (ART accelerator enabled except prefetch) running from Flash memory- V<sub>DD</sub> = 1.7 V**

Symbol	Parameter	Conditions	f <sub>HCLK</sub> (MHz)	Typ	Max <sup>(1)</sup>			Unit
					T <sub>A</sub> = 25 °C	T <sub>A</sub> = 85 °C	T <sub>A</sub> = 105 °C	
I <sub>DD</sub>	Supply current in <b>Run mode</b>	External clock, all peripherals enabled <sup>(2)(3)</sup>	84	23.2	24.5	25.6	26.6	mA
			60	15.1	16.3	17.4	18.4	
			40	10.8	12.1	13.2	14.2	
			30	8.8	10.0	11.1	12.2	
			20	6.9	8.0	9.0	10.1	
		External clock, all peripherals disabled <sup>(3)</sup>	84	12.3	13.6	14.7	15.7	
			60	8.2	9.4	10.5	11.5	
			40	6.0	7.3	8.3	9.4	
			30	4.9	6.2	7.2	8.3	
			20	4.0	5.1	6.1	7.2	

1. Guaranteed by characterization, not tested in production unless otherwise specified.
2. Add an additional power consumption of 1.6 mA per ADC for the analog part. In applications, this consumption occurs only while the ADC is ON (ADON bit is set in the ADC\_CR2 register).
3. When the ADC is ON (ADON bit set in the ADC\_CR2), add an additional power consumption of 1.6mA per ADC for the analog part.

**Table 23. Typical and maximum current consumption in run mode, code with data processing (ART accelerator enabled except prefetch) running from Flash memory - V<sub>DD</sub> = 3.3 V**

Symbol	Parameter	Conditions	f <sub>HCLK</sub> (MHz)	Typ	Max <sup>(1)</sup>			Unit
					T <sub>A</sub> = 25 °C	T <sub>A</sub> = 85 °C	T <sub>A</sub> = 105 °C	
I <sub>DD</sub>	Supply current in <b>Run mode</b>	External clock, all peripherals enabled <sup>(2)(3)</sup>	84	23.4	24.7	25.8	26.8	mA
			60	15.3	16.5	17.6	18.6	
			40	11.0	12.3	13.4	14.4	
			30	9.0	10.2	11.3	12.4	
			20	7.1	8.2	9.2	10.3	
		External clock, all peripherals disabled <sup>(3)</sup>	84	12.5	13.8	14.9	15.9	
			60	8.4	9.6	10.7	11.7	
			40	6.2	7.5	8.5	9.6	
			30	5.1	6.4	7.4	8.5	
			20	4.2	5.3	6.3	7.4	

1. Guaranteed by characterization, not tested in production unless otherwise specified.
2. Add an additional power consumption of 1.6 mA per ADC for the analog part. In applications, this consumption occurs only while the ADC is ON (ADON bit is set in the ADC\_CR2 register).
3. When the ADC is ON (ADON bit set in the ADC\_CR2), add an additional power consumption of 1.6mA per ADC for the analog part.

**Table 24. Typical and maximum current consumption in run mode, code with data processing (ART accelerator disabled) running from Flash memory**

Symbol	Parameter	Conditions	f <sub>HCLK</sub> (MHz)	Typ	Max <sup>(1)</sup>			Unit
					T <sub>A</sub> = 25 °C	T <sub>A</sub> = 85 °C	T <sub>A</sub> = 105 °C	
I <sub>DD</sub>	Supply current in <b>Run mode</b>	External clock, all peripherals enabled <sup>(2)(3)</sup>	84	31.1	32.2	34.3	36.3	mA
			60	21.7	22.1	23.2	24.2	
			40	15.5	16.1	17.1	18.1	
			30	12.6	13.1	14.1	15.1	
			20	9.8	10.1	11.1	12.1	
		External clock, all peripherals disabled <sup>(3)</sup>	84	20.2	21.3	23.4	25.4	
			60	14.9	15.3	16.3	17.3	
			40	10.6	11.2	12.2	13.3	
			30	8.8	9.2	10.2	11.2	
			20	6.9	7.2	8.2	9.2	

1. Guaranteed by characterization, not tested in production unless otherwise specified.
2. Add an additional power consumption of 1.6 mA per ADC for the analog part. In applications, this consumption occurs only while the ADC is ON (ADON bit is set in the ADC\_CR2 register).
3. When the ADC is ON (ADON bit set in the ADC\_CR2), add an additional power consumption of 1.6mA per ADC for the analog part.

**Table 25. Typical and maximum current consumption in run mode, code with data processing (ART accelerator enabled with prefetch) running from Flash memory**

Symbol	Parameter	Conditions	f <sub>HCLK</sub> (MHz)	Typ	Max <sup>(1)</sup>			Unit
					T <sub>A</sub> = 25 °C	T <sub>A</sub> = 85 °C	T <sub>A</sub> = 105 °C	
I <sub>DD</sub>	Supply current in <b>Run mode</b>	External clock, all peripherals enabled <sup>(2)(3)</sup>	84	32.5	33.3	34.3	35.4	mA
			60	22.2	23.3	24.3	25.3	
			40	16.0	17.1	18.1	19.2	
			30	12.9	14.1	15.1	16.1	
			20	10.2	11.1	12.1	13.1	
		External clock, all peripherals disabled <sup>(3)</sup>	84	21.6	22.4	23.5	24.5	
			60	15.3	16.4	17.4	18.4	
			40	11.2	12.3	13.3	14.3	
			30	9.0	10.2	11.2	12.3	
			20	7.3	8.2	9.2	10.2	

1. Guaranteed by characterization, not tested in production unless otherwise specified.
2. Add an additional power consumption of 1.6 mA per ADC for the analog part. In applications, this consumption occurs only while the ADC is ON (ADON bit is set in the ADC\_CR2 register).
3. When the ADC is ON (ADON bit set in the ADC\_CR2), add an additional power consumption of 1.6mA per ADC for the analog part.

**Table 26. Typical and maximum current consumption in Sleep mode**

Symbol	Parameter	Conditions	f <sub>HCLK</sub> (MHz)	Typ	Max <sup>(1)</sup>			Unit
					T <sub>A</sub> = 25 °C	T <sub>A</sub> = 85 °C	T <sub>A</sub> = 105 °C	
I <sub>DD</sub>	Supply current in <b>Sleep</b> mode	External clock, all peripherals enabled <sup>(2)(3)</sup>	84	16.6	17.4	18.4	19.5	mA
			60	10.8	11.2	12.3	13.3	
			40	8.3	9.0	10.0	11.0	
			30	6.8	7.1	8.1	9.1	
			20	5.9	6.1	7.1	8.1	
		External clock, all peripherals disabled <sup>(3)(4)</sup>	84	5.3	6.1	7.1	8.2	
			60	3.7	4.1	5.1	6.1	
			40	2.9	3.1	4.1	5.1	
			30	2.7	3.1	4.1	5.1	
			20	2.7	3.1	4.1	5.1	

1. Guaranteed by characterization, not tested in production unless otherwise specified.
2. Add an additional power consumption of 1.6 mA per ADC for the analog part. In applications, this consumption occurs only while the ADC is ON (ADON bit is set in the ADC\_CR2 register).
3. When the ADC is ON (ADON bit set in the ADC\_CR2 register), add an additional power consumption of 1.6 mA for the analog part.
4. Same current consumption for f<sub>HCLK</sub> at 30 MHz and 20 MHz due to VCO running slower at 30 MHz.

**Table 27. Typical and maximum current consumptions in Stop mode - V<sub>DD</sub>=1.8 V**

Symbol	Parameter	Conditions	Typ	Max <sup>(1)</sup>				Unit
				T <sub>A</sub> = 25 °C	T <sub>A</sub> = 25 °C	T <sub>A</sub> = 85 °C	T <sub>A</sub> = 105 °C	
I <sub>DD_STOP</sub>	Main regulator usage	Flash in Stop mode, all oscillators OFF, no independent watchdog	109	135	440	650	µA	
	Low power regulator usage		41	65	310	530 <sup>(2)</sup>		
	Main regulator usage	Flash in Deep power down mode, all oscillators OFF, no independent watchdog	72	95	345	530		
	Low power regulator usage		12	36	260	510 <sup>(2)</sup>		
	Low power low voltage regulator usage		10	27	230	460		

1. Guaranteed by characterization, not tested in production.
2. Guaranteed by test in production.

**Table 28. Typical and maximum current consumption in Stop mode - V<sub>DD</sub>=3.3 V**

Symbol	Parameter	Conditions	Typ	Max <sup>(1)</sup>				Unit
			T <sub>A</sub> = 25 °C	T <sub>A</sub> = 25 °C	T <sub>A</sub> = 85 °C	T <sub>A</sub> = 105 °C		
I <sub>DD_STOP</sub>	Main regulator usage	Flash in Stop mode, all oscillators OFF, no independent watchdog	111	140	450	670	μA	
	Low power regulator usage		42	65	330	560		
	Main regulator usage	Flash in Deep power down mode, all oscillators OFF, no independent watchdog	73	100	360	560		
	Low power regulator usage		12	36	270	520		
	Low power low voltage regulator usage		10	28	230	470		

1. Guaranteed by characterization, not tested in production.

**Table 29. Typical and maximum current consumption in Standby mode - V<sub>DD</sub>=1.8 V**

Symbol	Parameter	Conditions	Typ <sup>(1)</sup>	Max <sup>(2)</sup>				Unit
			T <sub>A</sub> = 25 °C	T <sub>A</sub> = 25 °C	T <sub>A</sub> = 85 °C	T <sub>A</sub> = 105 °C		
I <sub>DD_STBY</sub>	Supply current in Standby mode	Low-speed oscillator (LSE) and RTC ON	2.4	4.0	12.0	24.0	μA	
		RTC and LSE OFF	1.8	3.0 <sup>(3)</sup>	11.0	23.0 <sup>(3)</sup>		

1. When the PDR is OFF (internal reset is OFF), the typical current consumption is reduced by 1.2 μA.
2. Guaranteed by characterization, not tested in production unless otherwise specified.
3. Guaranteed by test in production.

**Table 30. Typical and maximum current consumption in Standby mode - V<sub>DD</sub>=3.3 V**

Symbol	Parameter	Conditions	Typ <sup>(1)</sup>	Max <sup>(2)</sup>				Unit
			T <sub>A</sub> = 25 °C	T <sub>A</sub> = 25 °C	T <sub>A</sub> = 85 °C	T <sub>A</sub> = 105 °C		
I <sub>DD_STBY</sub>	Supply current in Standby mode	Low-speed oscillator (LSE) and RTC ON	2.8	5.0	14.0	28.0	μA	
		RTC and LSE OFF	2.1	4.0 <sup>(3)</sup>	13.0	27.0 <sup>(3)</sup>		

1. When the PDR is OFF (internal reset is OFF), the typical current consumption is reduced by 1.2 μA.
2. Guaranteed by characterization, not tested in production unless otherwise specified.
3. Guaranteed by test in production.

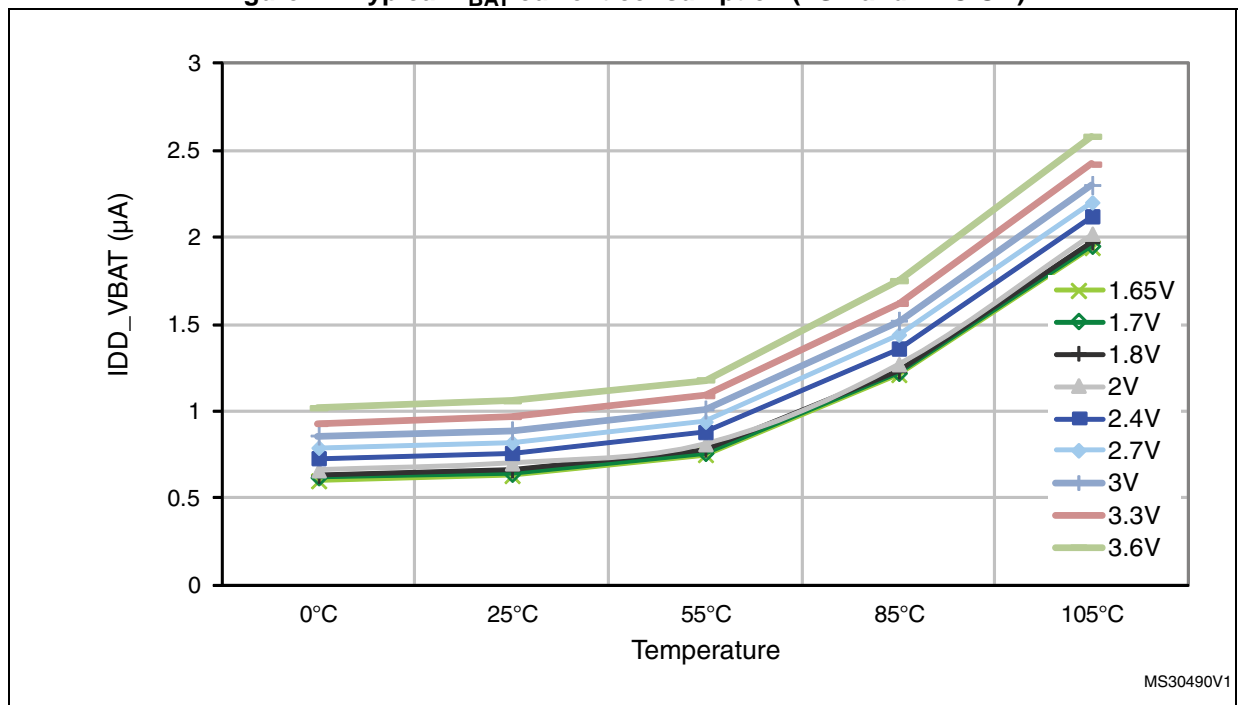
Table 31. Typical and maximum current consumptions in V<sub>BAT</sub> mode

Symbol	Parameter	Conditions <sup>(1)</sup>	Typ			Max <sup>(2)</sup>		Unit
			T <sub>A</sub> = 25 °C			T <sub>A</sub> = 85 °C	T <sub>A</sub> = 105 °C	
			V <sub>BAT</sub> = 1.7 V	V <sub>BAT</sub> = 2.4 V	V <sub>BAT</sub> = 3.3 V	V <sub>BAT</sub> = 3.6 V		
I <sub>DD_VBAT</sub>	Backup domain supply current	Low-speed oscillator (LSE) and RTC ON	0.66	0.76	0.97	3.0	5.0	μA
		RTC and LSE OFF	0.1	0.1	0.1	2.0	4.0	

1. Crystal used: Abracon ABS07-120-32.768 kHz-T with a C<sub>L</sub> of 6 pF for typical values.

2. Guaranteed by characterization, not tested in production.

Figure 21. Typical V<sub>BAT</sub> current consumption (LSE and RTC ON)



**I/O system current consumption**

The current consumption of the I/O system has two components: static and dynamic.

**I/O static current consumption**

All the I/Os used as inputs with pull-up generate current consumption when the pin is externally held low. The value of this current consumption can be simply computed by using the pull-up/pull-down resistors values given in [Table 54: I/O static characteristics](#).

For the output pins, any external pull-down or external load must also be considered to estimate the current consumption.

Additional I/O current consumption is due to I/Os configured as inputs if an intermediate voltage level is externally applied. This current consumption is caused by the input Schmitt trigger circuits used to discriminate the input value. Unless this specific configuration is



required by the application, this supply current consumption can be avoided by configuring these I/Os in analog mode. This is notably the case of ADC input pins which should be configured as analog inputs.

**Caution:** Any floating input pin can also settle to an intermediate voltage level or switch inadvertently, as a result of external electromagnetic noise. To avoid current consumption related to floating pins, they must either be configured in analog mode, or forced internally to a definite digital value. This can be done either by using pull-up/down resistors or by configuring the pins in output mode.

#### I/O dynamic current consumption

In addition to the internal peripheral current consumption (see [Table 33: Peripheral current consumption](#)), the I/Os used by an application also contribute to the current consumption. When an I/O pin switches, it uses the current from the MCU supply voltage to supply the I/O pin circuitry and to charge/discharge the capacitive load (internal or external) connected to the pin:

$$I_{SW} = V_{DD} \times f_{SW} \times C$$

where

$I_{SW}$  is the current sunk by a switching I/O to charge/discharge the capacitive load

$V_{DD}$  is the MCU supply voltage

$f_{SW}$  is the I/O switching frequency

$C$  is the total capacitance seen by the I/O pin:  $C = C_{INT} + C_{EXT}$

The test pin is configured in push-pull output mode and is toggled by software at a fixed frequency.

Table 32. Switching output I/O current consumption

Symbol	Parameter	Conditions <sup>(1)</sup>	I/O toggling frequency (f <sub>SW</sub> )	Typ	Unit
IDDIO	I/O switching current	V <sub>DD</sub> = 3.3 V C = C <sub>INT</sub>	2 MHz	0.05	mA
			8 MHz	0.15	
			25 MHz	0.45	
			50 MHz	0.85	
			60 MHz	1.00	
			84 MHz	1.40	
		V <sub>DD</sub> = 3.3 V C <sub>EXT</sub> = 0 pF C = C <sub>INT</sub> + C <sub>EXT</sub> + C <sub>S</sub>	2 MHz	0.10	
			8 MHz	0.35	
			25 MHz	1.05	
			50 MHz	2.20	
			60 MHz	2.40	
			84 MHz	3.55	
		V <sub>DD</sub> = 3.3 V C <sub>EXT</sub> = 10 pF C = C <sub>INT</sub> + C <sub>EXT</sub> + C <sub>S</sub>	2 MHz	0.20	
			8 MHz	0.65	
			25 MHz	1.85	
			50 MHz	2.45	
			60 MHz	4.70	
		V <sub>DD</sub> = 3.3 V C <sub>EXT</sub> = 22 pF C = C <sub>INT</sub> + C <sub>EXT</sub> + C <sub>S</sub>	84 MHz	8.80	
			2 MHz	0.25	
			8 MHz	1.00	
			25 MHz	3.45	
		V <sub>DD</sub> = 3.3 V C <sub>EXT</sub> = 33 pF C = C <sub>INT</sub> + C <sub>EXT</sub> + C <sub>S</sub>	50 MHz	7.15	
			60 MHz	11.55	
			2 MHz	0.32	
8 MHz	1.27				
			25 MHz	3.88	
			50 MHz	12.34	

1. C<sub>S</sub> is the PCB board capacitance including the pad pin. C<sub>S</sub> = 7 pF (estimated value).

**On-chip peripheral current consumption**

The MCU is placed under the following conditions:

- At startup, all I/O pins are in analog input configuration.
- All peripherals are disabled unless otherwise mentioned.
- The ART accelerator is ON.
- Voltage Scale 2 mode selected, internal digital voltage V12 = 1.26 V.
- HCLK is the system clock at 84 MHz.  $f_{PCLK1} = f_{HCLK}/2$ , and  $f_{PCLK2} = f_{HCLK}$ .  
 The given value is calculated by measuring the difference of current consumption
  - with all peripherals clocked off
  - with only one peripheral clocked on
- Ambient operating temperature is 25 °C and  $V_{DD}=3.3$  V.

**Table 33. Peripheral current consumption**

Peripheral		I <sub>DD</sub> (typ)	Unit
<b>AHB1</b> (up to 84MHz)	GPIOA	1.55	μA/MHz
	GPIOB	1.55	
	GPIOC	1.55	
	GIOD	1.55	
	GPIOE	1.55	
	GPIOH	1.55	
	CRC	0.36	
	DMA1	20.24	
	DMA2	21.07	
<b>APB1</b> (up to 42MHz)	TIM2	11.19	μA/MHz
	TIM3	8.57	
	TIM4	8.33	
	TIM5	11.19	
	PWR	0.71	
	USART2	3.33	
	I2C1/2/3	3.10	
	SPI2 <sup>(1)</sup>	2.62	
	SPI3 <sup>(1)</sup>	2.86	
	I2S2	1.90	
	I2S3	1.67	
	WWDG	0.71	
<b>AHB2</b> (up to 84MHz)	OTG_FS	23.93	μA/MHz



**Table 33. Peripheral current consumption (continued)**

Peripheral		I <sub>DD</sub> (typ)	Unit
APB2 (up to 84MHz)	TIM1	5.71	μA/MHz
	TIM9	2.86	
	TIM10	1.79	
	TIM11	2.02	
	ADC1 <sup>(2)</sup>	2.98	
	SPI1	1.19	
	USART1	3.10	
	USART6	2.86	
	SDIO	5.95	
	SPI4	1.31	
	SYSCFG	0.71	

1. I2SMOD bit set in SPI\_I2SCFGR register, and then the I2SE bit set to enable I2S peripheral.
2. When the ADC is ON (ADON bit set in the ADC\_CR2 register), add an additional power consumption of 1.6 mA for the analog part.

### 6.3.7 Wakeup time from low-power modes

The wakeup times given in [Table 34](#) are measured starting from the wakeup event trigger up to the first instruction executed by the CPU:

- For Stop or Sleep modes: the wakeup event is WFE.
- WKUP (PA0) pin is used to wakeup from Standby, Stop and Sleep modes.

All timings are derived from tests performed under ambient temperature and V<sub>DD</sub>=3.3 V.

**Table 34. Low-power mode wakeup timings<sup>(1)</sup>**

Symbol	Parameter	Min <sup>(1)</sup>	Typ <sup>(1)</sup>	Max <sup>(1)</sup>	Unit
t <sub>WUSLEEP</sub> <sup>(2)</sup>	Wakeup from Sleep mode	-	4	6	CPU clock cycle
t <sub>WUSTOP</sub> <sup>(2)</sup>	Wakeup from Stop mode, usage of main regulator	-	13.5	14.5	μs
	Wakeup from Stop mode, usage of main regulator, Flash memory in Deep power down mode	-	105	111	
	Wakeup from Stop mode, regulator in low power mode	-	21	33	
	Wakeup from Stop mode, regulator in low power mode, Flash memory in Deep power down mode	-	113	130	
t <sub>WUSTDBY</sub> <sup>(2)(3)</sup>	Wakeup from Standby mode	-	314	407	μs

1. Guaranteed by characterization, not tested in production.
2. The wakeup times are measured from the wakeup event to the point in which the application code reads the first instruction.
3. t<sub>WUSTDBY</sub> maximum value is given at -40 °C.

### 6.3.8 External clock source characteristics

#### High-speed external user clock generated from an external source

In bypass mode the HSE oscillator is switched off and the input pin is a standard I/O. The external clock signal has to respect the [Table 54](#). However, the recommended clock input waveform is shown in [Figure 22](#).

The characteristics given in [Table 35](#) result from tests performed using an high-speed external clock source, and under ambient temperature and supply voltage conditions summarized in [Table 14](#).

**Table 35. High-speed external user clock characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$f_{\text{HSE\_ext}}$	External user clock source frequency <sup>(1)</sup>		1	-	50	MHz
$V_{\text{HSEH}}$	OSC_IN input pin high level voltage		$0.7V_{\text{DD}}$	-	$V_{\text{DD}}$	V
$V_{\text{HSEL}}$	OSC_IN input pin low level voltage		$V_{\text{SS}}$	-	$0.3V_{\text{DD}}$	
$t_{\text{w(HSE)}}$ $t_{\text{w(HSE)}}$	OSC_IN high or low time <sup>(1)</sup>		5	-	-	ns
$t_{\text{r(HSE)}}$ $t_{\text{f(HSE)}}$	OSC_IN rise or fall time <sup>(1)</sup>		-	-	10	
$C_{\text{in(HSE)}}$	OSC_IN input capacitance <sup>(1)</sup>		-	5	-	pF
$\text{DuCy}_{\text{(HSE)}}$	Duty cycle		45	-	55	%
$I_{\text{L}}$	OSC_IN Input leakage current	$V_{\text{SS}} \leq V_{\text{IN}} \leq V_{\text{DD}}$	-	-	$\pm 1$	$\mu\text{A}$

1. Guaranteed by design, not tested in production.

#### Low-speed external user clock generated from an external source

In bypass mode the LSE oscillator is switched off and the input pin is a standard I/O. The external clock signal has to respect the [Table 54](#). However, the recommended clock input waveform is shown in [Figure 23](#).

The characteristics given in [Table 36](#) result from tests performed using an low-speed external clock source, and under ambient temperature and supply voltage conditions summarized in [Table 14](#).

Table 36. Low-speed external user clock characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$f_{LSE\_ext}$	User External clock source frequency <sup>(1)</sup>		-	32.768	1000	kHz
$V_{LSEH}$	OSC32_IN input pin high level voltage		$0.7V_{DD}$	-	$V_{DD}$	V
$V_{LSEL}$	OSC32_IN input pin low level voltage		$V_{SS}$	-	$0.3V_{DD}$	
$t_{w(LSE)}$ $t_{f(LSE)}$	OSC32_IN high or low time <sup>(1)</sup>		450	-	-	ns
$t_{r(LSE)}$ $t_{f(LSE)}$	OSC32_IN rise or fall time <sup>(1)</sup>		-	-	50	
$C_{in(LSE)}$	OSC32_IN input capacitance <sup>(1)</sup>		-	5	-	pF
DuCy <sub>(LSE)</sub>	Duty cycle		30	-	70	%
$I_L$	OSC32_IN Input leakage current	$V_{SS} \leq V_{IN} \leq V_{DD}$	-	-	$\pm 1$	$\mu A$

1. Guaranteed by design, not tested in production.

Figure 22. High-speed external clock source AC timing diagram

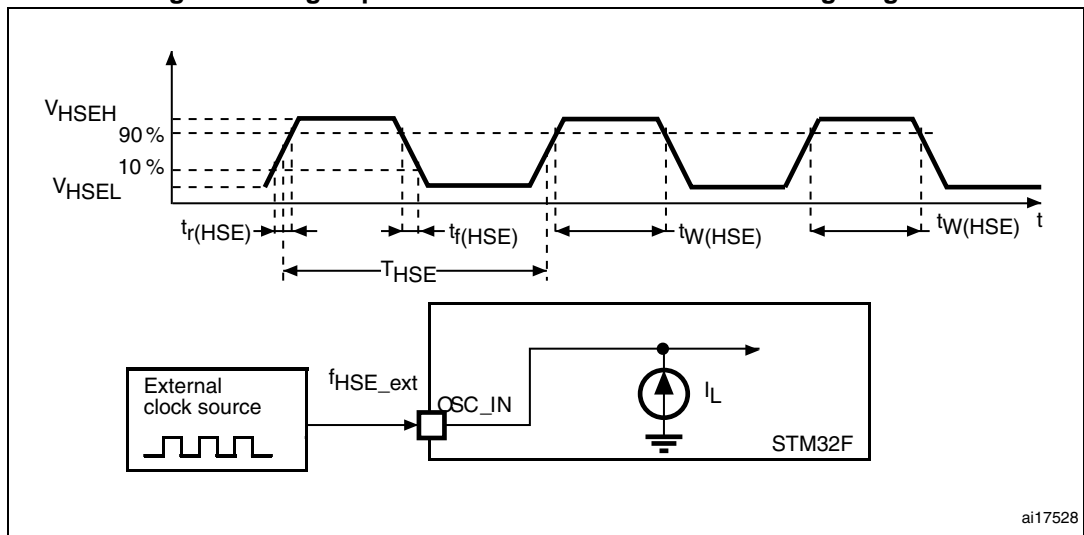
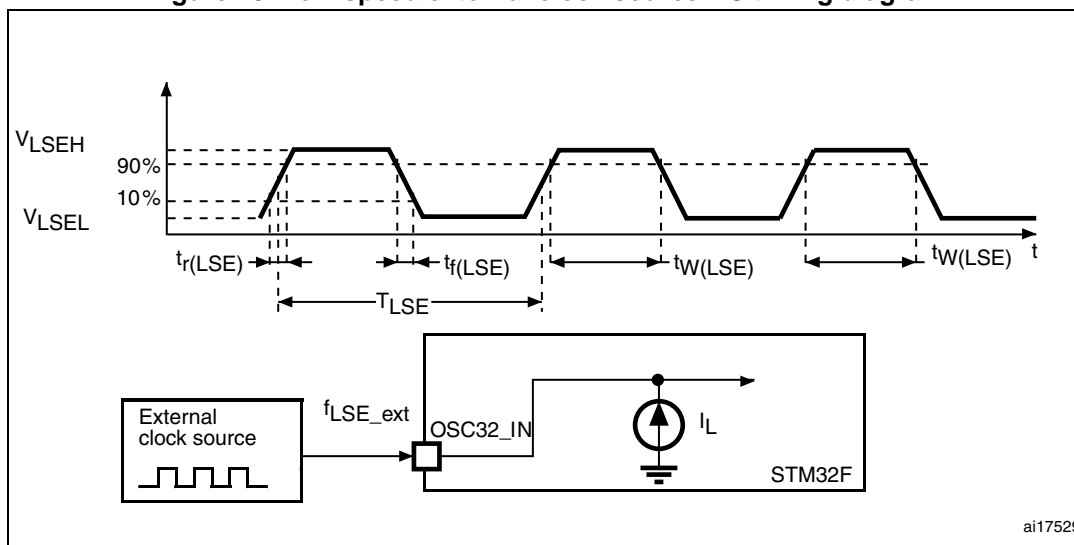


Figure 23. Low-speed external clock source AC timing diagram



**High-speed external clock generated from a crystal/ceramic resonator**

The high-speed external (HSE) clock can be supplied with a 4 to 26 MHz crystal/ceramic resonator oscillator. All the information given in this paragraph are based on characterization results obtained with typical external components specified in [Table 37](#). In the application, the resonator and the load capacitors have to be placed as close as possible to the oscillator pins in order to minimize output distortion and startup stabilization time. Refer to the crystal resonator manufacturer for more details on the resonator characteristics (frequency, package, accuracy).

Table 37. HSE 4-26 MHz oscillator characteristics<sup>(1)</sup>

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f <sub>OSC_IN</sub>	Oscillator frequency		4	-	26	MHz
R <sub>F</sub>	Feedback resistor		-	200	-	kΩ
I <sub>DD</sub>	HSE current consumption	V <sub>DD</sub> =3.3 V, ESR= 30 Ω, C <sub>L</sub> =5 pF @25 MHz	-	450	-	μA
		V <sub>DD</sub> =3.3 V, ESR= 30 Ω, C <sub>L</sub> =10 pF @25 MHz	-	530	-	
G <sub>m_crit_max</sub>	Maximum critical crystal g <sub>m</sub>	Startup	-	-	1	mA/V
t <sub>SU(HSE)</sub> <sup>(2)</sup>	Startup time	V <sub>DD</sub> is stabilized	-	2	-	ms

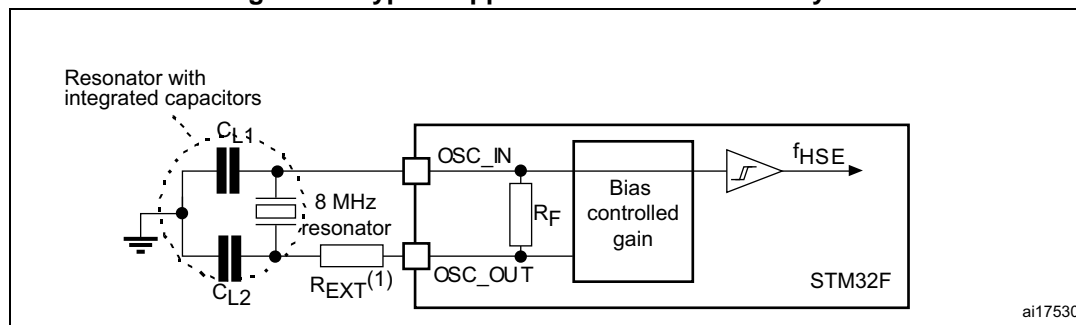
1. Guaranteed by design, not tested in production.
2. t<sub>SU(HSE)</sub> is the startup time measured from the moment it is enabled (by software) to a stabilized 8 MHz oscillation is reached. This value is measured for a standard crystal resonator and it can vary significantly with the crystal manufacturer

For C<sub>L1</sub> and C<sub>L2</sub>, it is recommended to use high-quality external ceramic capacitors in the 5 pF to 25 pF range (typ.), designed for high-frequency applications, and selected to match the requirements of the crystal or resonator (see [Figure 24](#)). C<sub>L1</sub> and C<sub>L2</sub> are usually the same size. The crystal manufacturer typically specifies a load capacitance which is the

series combination of  $C_{L1}$  and  $C_{L2}$ . PCB and MCU pin capacitance must be included (10 pF can be used as a rough estimate of the combined pin and board capacitance) when sizing  $C_{L1}$  and  $C_{L2}$ .

*Note:* For information on selecting the crystal, refer to the application note AN2867 “Oscillator design guide for ST microcontrollers” available from the ST website [www.st.com](http://www.st.com).

**Figure 24. Typical application with an 8 MHz crystal**



1.  $R_{EXT}$  value depends on the crystal characteristics.

**Low-speed external clock generated from a crystal/ceramic resonator**

The low-speed external (LSE) clock can be supplied with a 32.768 kHz crystal/ceramic resonator oscillator. All the information given in this paragraph are based on characterization results obtained with typical external components specified in [Table 38](#). In the application, the resonator and the load capacitors have to be placed as close as possible to the oscillator pins in order to minimize output distortion and startup stabilization time. Refer to the crystal resonator manufacturer for more details on the resonator characteristics (frequency, package, accuracy).

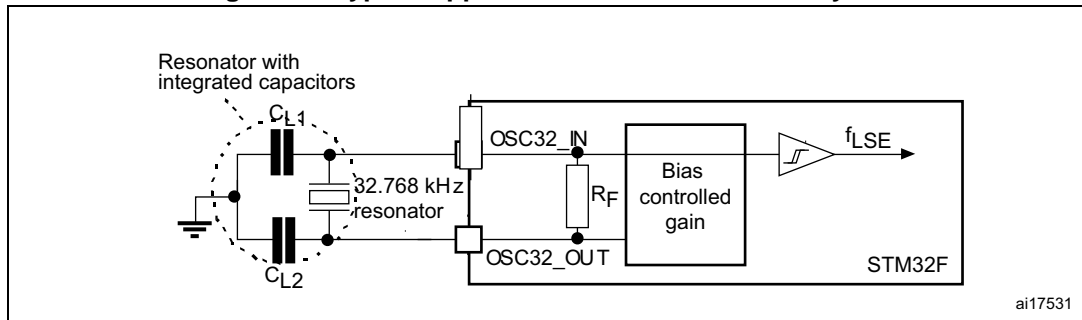
**Table 38. LSE oscillator characteristics ( $f_{LSE} = 32.768$  kHz) <sup>(1)</sup>**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_F$	Feedback resistor		-	18.4	-	MΩ
$I_{DD}$	LSE current consumption		-	-	1	μA
$G_{m\_crit\_max}$	Maximum critical crystal $g_m$	Startup	-	-	0.56	μA/V
$t_{SU(LSE)}^{(2)}$	startup time	$V_{DD}$ is stabilized	-	2	-	s

1. Guaranteed by design, not tested in production.
2.  $t_{SU(LSE)}$  is the startup time measured from the moment it is enabled (by software) to a stabilized 32.768 kHz oscillation is reached. This value is guaranteed by characterization and not tested in production. It is measured for a standard crystal resonator and it can vary significantly with the crystal manufacturer.

*Note:* For information on selecting the crystal, refer to the application note AN2867 “Oscillator design guide for ST microcontrollers” available from the ST website [www.st.com](http://www.st.com).

Figure 25. Typical application with a 32.768 kHz crystal



### 6.3.9 Internal clock source characteristics

The parameters given in [Table 39](#) and [Table 40](#) are derived from tests performed under ambient temperature and  $V_{DD}$  supply voltage conditions summarized in [Table 14](#).

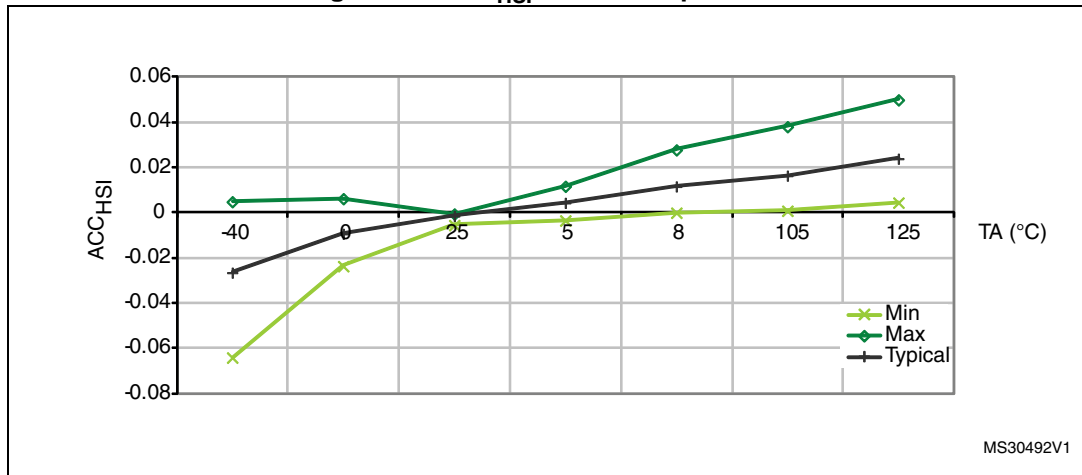
#### High-speed internal (HSI) RC oscillator

Table 39. HSI oscillator characteristics (1)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
$f_{HSI}$	Frequency		-	16	-	MHz	
$ACC_{HSI}$	Accuracy of the HSI oscillator	User-trimmed with the RCC_CR register <sup>(2)</sup>	-	-	1	%	
		Factory-calibrated	$T_A = -40$ to $105$ °C <sup>(3)</sup>	-8	-	4.5	%
			$T_A = -10$ to $85$ °C <sup>(3)</sup>	-4	-	4	%
$t_{su(HSI)}^{(2)}$	HSI oscillator startup time		-	2.2	4	μs	
$I_{DD(HSI)}^{(2)}$	HSI oscillator power consumption		-	60	80	μA	

- $V_{DD} = 3.3$  V,  $T_A = -40$  to  $105$  °C unless otherwise specified.
- Guaranteed by design, not tested in production
- Guaranteed by characterization, not tested in production

Figure 26. ACC<sub>HSI</sub> versus temperature



1. Guaranteed by characterization, not tested in production.

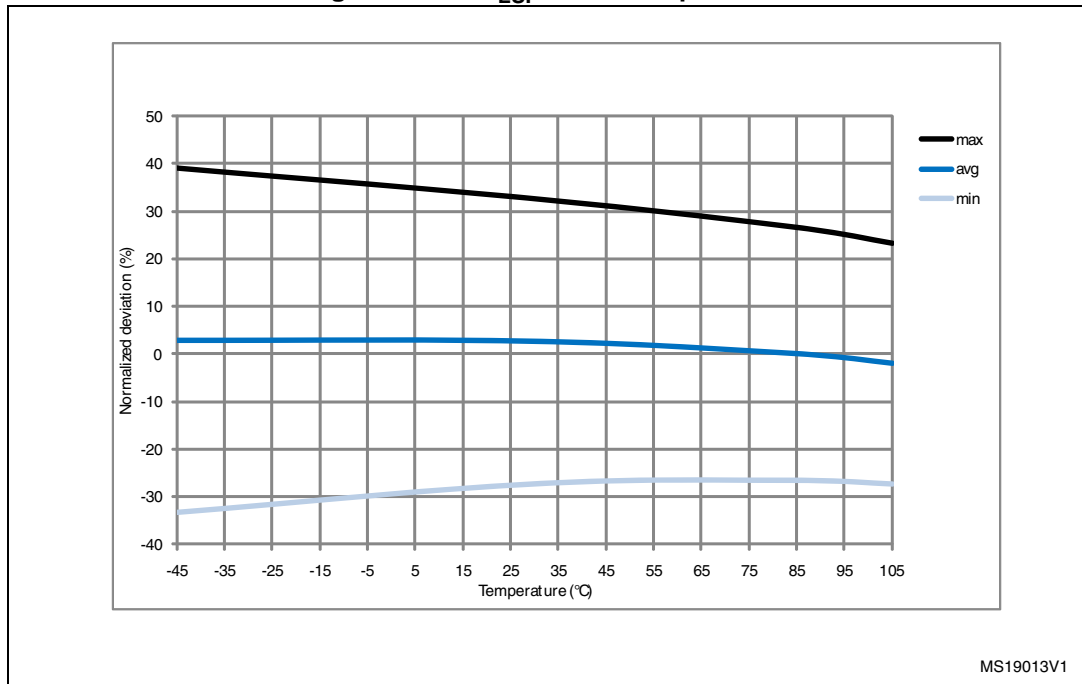
Low-speed internal (LSI) RC oscillator

Table 40. LSI oscillator characteristics (1)

Symbol	Parameter	Min	Typ	Max	Unit
f <sub>LSI</sub> <sup>(2)</sup>	Frequency	17	32	47	kHz
t <sub>su(LSI)</sub> <sup>(3)</sup>	LSI oscillator startup time	-	15	40	µs
I <sub>DD(LSI)</sub> <sup>(3)</sup>	LSI oscillator power consumption	-	0.4	0.6	µA

- V<sub>DD</sub> = 3 V, T<sub>A</sub> = -40 to 105 °C unless otherwise specified.
- Guaranteed by characterization, not tested in production.
- Guaranteed by design, not tested in production.

Figure 27. ACC<sub>LSI</sub> versus temperature



### 6.3.10 PLL characteristics

The parameters given in [Table 41](#) and [Table 42](#) are derived from tests performed under temperature and V<sub>DD</sub> supply voltage conditions summarized in [Table 14](#).

Table 41. Main PLL characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
f <sub>PLL_IN</sub>	PLL input clock <sup>(1)</sup>		0.95 <sup>(2)</sup>	1	2.10	MHz	
f <sub>PLL_OUT</sub>	PLL multiplier output clock		24	-	84	MHz	
f <sub>PLL48_OUT</sub>	48 MHz PLL multiplier output clock		-	48	75	MHz	
f <sub>VCO_OUT</sub>	PLL VCO output		192	-	432	MHz	
t <sub>LOCK</sub>	PLL lock time	VCO freq = 192 MHz	75	-	200	μs	
		VCO freq = 432 MHz	100	-	300		
Jitter <sup>(3)</sup>	Cycle-to-cycle jitter	System clock 84 MHz	RMS	-	25	-	ps
			peak to peak	-	±150	-	
	Period Jitter		RMS	-	15	-	
			peak to peak	-	±200	-	



Table 41. Main PLL characteristics (continued)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{DD(PLL)}^{(4)}$	PLL power consumption on VDD	VCO freq = 192 MHz VCO freq = 432 MHz	0.15 0.45	-	0.40 0.75	mA
$I_{DDA(PLL)}^{(4)}$	PLL power consumption on VDDA	VCO freq = 192 MHz VCO freq = 432 MHz	0.30 0.55	-	0.40 0.85	

1. Take care of using the appropriate division factor M to obtain the specified PLL input clock values. The M factor is shared between PLL and PLLI2S.
2. Guaranteed by design, not tested in production.
3. The use of 2 PLLs in parallel could degraded the Jitter up to +30%.
4. Guaranteed by characterization, not tested in production.

Table 42. PLLI2S (audio PLL) characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
$f_{PLL I2S\_IN}$	PLLI2S input clock <sup>(1)</sup>		0.95 <sup>(2)</sup>	1	2.10	MHz	
$f_{PLL I2S\_OUT}$	PLLI2S multiplier output clock		-	-	216		
$f_{VCO\_OUT}$	PLLI2S VCO output		192	-	432		
$t_{LOCK}$	PLLI2S lock time	VCO freq = 192 MHz	75	-	200	µs	
		VCO freq = 432 MHz	100	-	300		
Jitter <sup>(3)</sup>	Master I2S clock jitter	Cycle to cycle at 12.288 MHz on 48 KHz period, N=432, R=5	RMS	-	90	-	ps
			peak to peak	-	±280	-	
		Average frequency of 12.288 MHz N = 432, R = 5 on 1000 samples	-	90	-		
	WS I2S clock jitter	Cycle to cycle at 48 KHz on 1000 samples	-	400	-		
$I_{DD(PLLI2S)}^{(4)}$	PLLI2S power consumption on V <sub>DD</sub>	VCO freq = 192 MHz	0.15	-	0.40	mA	
		VCO freq = 432 MHz	0.45	-	0.75		
$I_{DDA(PLLI2S)}^{(4)}$	PLLI2S power consumption on V <sub>DDA</sub>	VCO freq = 192 MHz	0.30	-	0.40	mA	
		VCO freq = 432 MHz	0.55	-	0.85		

1. Take care of using the appropriate division factor M to have the specified PLL input clock values.
2. Guaranteed by design, not tested in production.
3. Value given with main PLL running.
4. Guaranteed by characterization, not tested in production.

### 6.3.11 PLL spread spectrum clock generation (SSCG) characteristics

The spread spectrum clock generation (SSCG) feature allows to reduce electromagnetic interferences (see [Table 49: EMI characteristics for WLCSP49](#)). It is available only on the main PLL.

**Table 43. SSCG parameters constraint**

Symbol	Parameter	Min	Typ	Max <sup>(1)</sup>	Unit
$f_{Mod}$	Modulation frequency	-	-	10	KHz
md	Peak modulation depth	0.25	-	2	%
MODEPER * INCSTEP		-	-	$2^{15}-1$	-

1. Guaranteed by design, not tested in production.

#### Equation 1

The frequency modulation period (MODEPER) is given by the equation below:

$$\text{MODEPER} = \text{round}[f_{\text{PLL\_IN}} / (4 \times f_{\text{Mod}})]$$

$f_{\text{PLL\_IN}}$  and  $f_{\text{Mod}}$  must be expressed in Hz.

As an example:

If  $f_{\text{PLL\_IN}} = 1 \text{ MHz}$ , and  $f_{\text{MOD}} = 1 \text{ kHz}$ , the modulation depth (MODEPER) is given by equation 1:

$$\text{MODEPER} = \text{round}[10^6 / (4 \times 10^3)] = 250$$

#### Equation 2

Equation 2 allows to calculate the increment step (INCSTEP):

$$\text{INCSTEP} = \text{round}[(2^{15} - 1) \times \text{md} \times \text{PLL}_N / (100 \times 5 \times \text{MODEPER})]$$

$f_{\text{VCO\_OUT}}$  must be expressed in MHz.

With a modulation depth (md) =  $\pm 2 \%$  (4 % peak to peak), and  $\text{PLL}_N = 240$  (in MHz):

$$\text{INCSTEP} = \text{round}[(2^{15} - 1) \times 2 \times 240 / (100 \times 5 \times 250)] = 126 \text{md}(\text{quantitized})\%$$

An amplitude quantization error may be generated because the linear modulation profile is obtained by taking the quantized values (rounded to the nearest integer) of MODEPER and INCSTEP. As a result, the achieved modulation depth is quantized. The percentage quantized modulation depth is given by the following formula:

$$\text{md}_{\text{quantized}}\% = (\text{MODEPER} \times \text{INCSTEP} \times 100 \times 5) / ((2^{15} - 1) \times \text{PLL}_N)$$

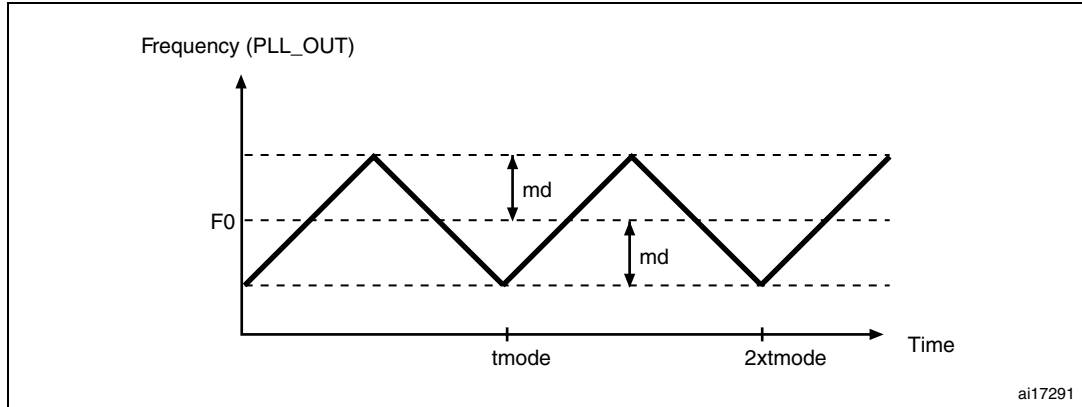
As a result:

$$\text{md}_{\text{quantized}}\% = (250 \times 126 \times 100 \times 5) / ((2^{15} - 1) \times 240) = 2,002\%(\text{peak})$$

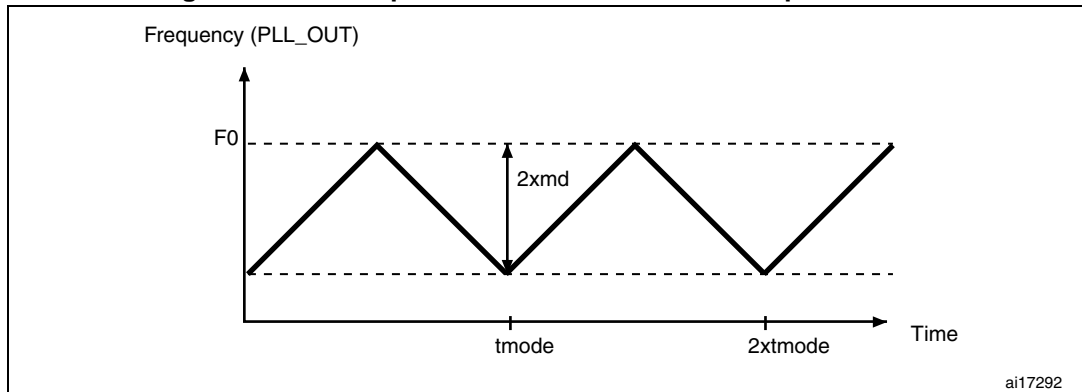
Figure 28 and Figure 29 show the main PLL output clock waveforms in center spread and down spread modes, where:

- F0 is  $f_{PLL\_OUT}$  nominal.
- $T_{mode}$  is the modulation period.
- md is the modulation depth.

**Figure 28. PLL output clock waveforms in center spread mode**



**Figure 29. PLL output clock waveforms in down spread mode**



### 6.3.12 Memory characteristics

#### Flash memory

The characteristics are given at  $T_A = -40$  to  $105$  °C unless otherwise specified.

The devices are shipped to customers with the Flash memory erased.

**Table 44. Flash memory characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{DD}$	Supply current	Write / Erase 8-bit mode, $V_{DD} = 1.7$ V	-	5	-	mA
		Write / Erase 16-bit mode, $V_{DD} = 2.1$ V	-	8	-	
		Write / Erase 32-bit mode, $V_{DD} = 3.3$ V	-	12	-	

Table 45. Flash memory programming

Symbol	Parameter	Conditions	Min <sup>(1)</sup>	Typ	Max <sup>(1)</sup>	Unit
$t_{prog}$	Word programming time	Program/erase parallelism (PSIZE) = x 8/16/32	-	16	100 <sup>(2)</sup>	$\mu s$
$t_{ERASE16KB}$	Sector (16 KB) erase time	Program/erase parallelism (PSIZE) = x 8	-	400	800	ms
		Program/erase parallelism (PSIZE) = x 16	-	300	600	
		Program/erase parallelism (PSIZE) = x 32	-	250	500	
$t_{ERASE64KB}$	Sector (64 KB) erase time	Program/erase parallelism (PSIZE) = x 8	-	1200	2400	ms
		Program/erase parallelism (PSIZE) = x 16	-	700	1400	
		Program/erase parallelism (PSIZE) = x 32	-	550	1100	
$t_{ERASE128KB}$	Sector (128 KB) erase time	Program/erase parallelism (PSIZE) = x 8	-	2	4	s
		Program/erase parallelism (PSIZE) = x 16	-	1.3	2.6	
		Program/erase parallelism (PSIZE) = x 32	-	1	2	
$t_{ME}$	Mass erase time	Program/erase parallelism (PSIZE) = x 8	-	8	16	s
		Program/erase parallelism (PSIZE) = x 16	-	5.5	11	
		Program/erase parallelism (PSIZE) = x 32	-	4	8	
$V_{prog}$	Programming voltage	32-bit program operation	2.7	-	3.6	V
		16-bit program operation	2.1	-	3.6	V
		8-bit program operation	1.7	-	3.6	V

1. Guaranteed by characterization, not tested in production.
2. The maximum programming time is measured after 100K erase operations.

Table 46. Flash memory programming with  $V_{PP}$  voltage

Symbol	Parameter	Conditions	Min <sup>(1)</sup>	Typ	Max <sup>(1)</sup>	Unit
$t_{prog}$	Double word programming	$T_A = 0$ to $+40$ °C $V_{DD} = 3.3$ V $V_{PP} = 8.5$ V	-	16	100 <sup>(2)</sup>	$\mu s$
$t_{ERASE16KB}$	Sector (16 KB) erase time		-	230	-	ms
$t_{ERASE64KB}$	Sector (64 KB) erase time		-	490	-	
$t_{ERASE128KB}$	Sector (128 KB) erase time		-	875	-	
$t_{ME}$	Mass erase time		-	1.750	-	s

**Table 46. Flash memory programming with V<sub>PP</sub> voltage (continued)**

Symbol	Parameter	Conditions	Min <sup>(1)</sup>	Typ	Max <sup>(1)</sup>	Unit
V <sub>prog</sub>	Programming voltage		2.7	-	3.6	V
V <sub>PP</sub>	V <sub>PP</sub> voltage range		7	-	9	V
I <sub>PP</sub>	Minimum current sunk on the V <sub>PP</sub> pin		10	-	-	mA
t <sub>VPP</sub> <sup>(3)</sup>	Cumulative time during which V <sub>PP</sub> is applied		-	-	1	hour

1. Guaranteed by design, not tested in production.
2. The maximum programming time is measured after 100K erase operations.
3. V<sub>PP</sub> should only be connected during programming/erasing.

**Table 47. Flash memory endurance and data retention**

Symbol	Parameter	Conditions	Value	Unit
			Min <sup>(1)</sup>	
N <sub>END</sub>	Endurance	T <sub>A</sub> = -40 to +85 °C (6 suffix versions) T <sub>A</sub> = -40 to +105 °C (7 suffix versions)	10	kcycles
t <sub>RET</sub>	Data retention	1 kcycle <sup>(2)</sup> at T <sub>A</sub> = 85 °C	30	Years
		1 kcycle <sup>(2)</sup> at T <sub>A</sub> = 105 °C	10	
		10 kcycles <sup>(2)</sup> at T <sub>A</sub> = 55 °C	20	

1. Guaranteed by characterization, not tested in production.
2. Cycling performed over the whole temperature range.

### 6.3.13 EMC characteristics

Susceptibility tests are performed on a sample basis during device characterization.

#### Functional EMS (electromagnetic susceptibility)

While a simple application is executed on the device (toggling 2 LEDs through I/O ports), the device is stressed by two electromagnetic events until a failure occurs. The failure is indicated by the LEDs:

- **Electrostatic discharge (ESD)** (positive and negative) is applied to all device pins until a functional disturbance occurs. This test is compliant with the IEC 61000-4-2 standard.
- **FTB:** A burst of fast transient voltage (positive and negative) is applied to V<sub>DD</sub> and V<sub>SS</sub> through a 100 pF capacitor, until a functional disturbance occurs. This test is compliant with the IEC 61000-4-4 standard.

A device reset allows normal operations to be resumed.

The test results are given in [Table 48](#). They are based on the EMS levels and classes defined in application note AN1709.

Table 48. EMS characteristics for LQFP100 package

Symbol	Parameter	Conditions	Level/Class
$V_{FESD}$	Voltage limits to be applied on any I/O pin to induce a functional disturbance	$V_{DD} = 3.3$ V, LQFP100, WLCSP49, $T_A = +25$ °C, $f_{HCLK} = 84$ MHz, conforms to IEC 61000-4-2	2B
$V_{EFTB}$	Fast transient voltage burst limits to be applied through 100 pF on $V_{DD}$ and $V_{SS}$ pins to induce a functional disturbance	$V_{DD} = 3.3$ V, LQFP100, WLCSP49, $T_A = +25$ °C, $f_{HCLK} = 84$ MHz, conforms to IEC 61000-4-4	4A

When the application is exposed to a noisy environment, it is recommended to avoid pin exposition to disturbances. The pins showing a middle range robustness are: PA0, PA1, PA2, on LQFP100 packages and PDR\_ON on WLCSP49.

As a consequence, it is recommended to add a serial resistor (1 k $\Omega$  maximum) located as close as possible to the MCU to the pins exposed to noise (connected to tracks longer than 50 mm on PCB).

### Designing hardened software to avoid noise problems

EMC characterization and optimization are performed at component level with a typical application environment and simplified MCU software. It should be noted that good EMC performance is highly dependent on the user application and the software in particular.

Therefore it is recommended that the user applies EMC software optimization and prequalification tests in relation with the EMC level requested for his application.

#### Software recommendations

The software flowchart must include the management of runaway conditions such as:

- Corrupted program counter
- Unexpected reset
- Critical Data corruption (control registers...)

#### Prequalification trials

Most of the common failures (unexpected reset and program counter corruption) can be reproduced by manually forcing a low state on the NRST pin or the Oscillator pins for 1 second.

To complete these trials, ESD stress can be applied directly on the device, over the range of specification values. When unexpected behavior is detected, the software can be hardened to prevent unrecoverable errors occurring (see application note AN1015).

**Electromagnetic Interference (EMI)**

The electromagnetic field emitted by the device are monitored while a simple application, executing EEMBC code, is running. This emission test is compliant with SAE IEC61967-2 standard which specifies the test board and the pin loading.

**Table 49. EMI characteristics for WLCSP49**

Symbol	Parameter	Conditions	Monitored frequency band	Max vs. [f <sub>HSE</sub> /f <sub>CPU</sub> ]	Unit
				8/84 MHz	
S <sub>EMI</sub>	Peak level	V <sub>DD</sub> = 3.6 V, T <sub>A</sub> = 25 °C, conforming to IEC61967-2	0.1 to 30 MHz	-4	dBµV
			30 to 130 MHz	-4	
			130 MHz to 1 GHz	-2	
			SAE EMI Level	1.5	-

**Table 50. EMI characteristics for LQFP100**

Symbol	Parameter	Conditions	Monitored frequency band	Max vs. [f <sub>HSE</sub> /f <sub>CPU</sub> ]	Unit
				8/84 MHz	
S <sub>EMI</sub>	Peak level	V <sub>DD</sub> = 3.6 V, T <sub>A</sub> = 25 °C, conforming to IEC61967-2	0.1 to 30 MHz	19	dBµV
			30 to 130 MHz	19	
			130 MHz to 1 GHz	11	
			SAE EMI Level	3.5	-

**6.3.14 Absolute maximum ratings (electrical sensitivity)**

Based on three different tests (ESD, LU) using specific measurement methods, the device is stressed in order to determine its performance in terms of electrical sensitivity.

**Electrostatic discharge (ESD)**

Electrostatic discharges (a positive then a negative pulse separated by 1 second) are applied to the pins of each sample according to each pin combination. The sample size depends on the number of supply pins in the device (3 parts × (n+1) supply pins). This test conforms to the JESD22-A114/C101 standard.

**Table 51. ESD absolute maximum ratings**

Symbol	Ratings	Conditions	Class	Maximum value <sup>(1)</sup>	Unit
V <sub>ESD(HBM)</sub>	Electrostatic discharge voltage (human body model)	T <sub>A</sub> = +25 °C conforming to JESD22-A114	2	2000	V
V <sub>ESD(CDM)</sub>	Electrostatic discharge voltage (charge device model)	T <sub>A</sub> = +25 °C conforming to ANSI/ESD STM5.3.1	II	400	

1. Guaranteed by characterization, not tested in production.

**Static latchup**

Two complementary static tests are required on six parts to assess the latchup performance:

- A supply overvoltage is applied to each power supply pin
- A current injection is applied to each input, output and configurable I/O pin

These tests are compliant with EIA/JESD 78A IC latchup standard.

**Table 52. Electrical sensitivities**

Symbol	Parameter	Conditions	Class
LU	Static latch-up class	T <sub>A</sub> = +105 °C conforming to JESD78A	II level A

**6.3.15 I/O current injection characteristics**

As a general rule, current injection to the I/O pins, due to external voltage below V<sub>SS</sub> or above V<sub>DD</sub> (for standard, 3 V-capable I/O pins) should be avoided during normal product operation. However, in order to give an indication of the robustness of the microcontroller in cases when abnormal injection accidentally happens, susceptibility tests are performed on a sample basis during device characterization.

**Functional susceptibility to I/O current injection**

While a simple application is executed on the device, the device is stressed by injecting current into the I/O pins programmed in floating input mode. While current is injected into the I/O pin, one at a time, the device is checked for functional failures.

The failure is indicated by an out of range parameter: ADC error above a certain limit (>5 LSB TUE), out of conventional limits of induced leakage current on adjacent pins (out of -5 μA/+0 μA range), or other functional failure (for example reset, oscillator frequency deviation).

Negative induced leakage current is caused by negative injection and positive induced leakage current by positive injection.

The test results are given in [Table 53](#).



**Table 53. I/O current injection susceptibility<sup>(1)</sup>**

Symbol	Description	Functional susceptibility		Unit
		Negative injection	Positive injection	
I <sub>INJ</sub>	Injected current on BOOT0 pin	-0	NA	mA
	Injected current on NRST pin	-0	NA	
	Injected current on PB3, PB4, PB5, PB6, PB7, PB8, PB9, PC13, PC14, PC15, PH1, PDR_ON, PC0, PC1, PC2, PC3, PD1, PD5, PD6, PD7, PE0, PE2, PE3, PE4, PE5, PE6	-0	NA	
	Injected current on any other FT pin	-5	NA	
	Injected current on any other pins	-5	+5	

1. NA = not applicable.

*Note: It is recommended to add a Schottky diode (pin to ground) to analog pins which may potentially inject negative currents.*

### 6.3.16 I/O port characteristics

#### General input/output characteristics

Unless otherwise specified, the parameters given in [Table 54](#) are derived from tests performed under the conditions summarized in [Table 14](#). All I/Os are CMOS and TTL compliant.

**Table 54. I/O static characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V <sub>IL</sub>	FT, and NRST I/O input low level voltage	1.7 V ≤ V <sub>DD</sub> ≤ 3.6 V	-	-	0.35V <sub>DD</sub> -0.04 <sup>(1)</sup>	V
					0.3V <sub>DD</sub> <sup>(2)</sup>	
	BOOT0 I/O input low level voltage	1.75 V ≤ V <sub>DD</sub> ≤ 3.6 V, -40 °C ≤ T <sub>A</sub> ≤ 105 °C	-	-	0.1V <sub>DD</sub> +0.1	
		1.7 V ≤ V <sub>DD</sub> ≤ 3.6 V, 0 °C ≤ T <sub>A</sub> ≤ 105 °C	-	-		
V <sub>IH</sub>	FT and NRST I/O input high level voltage <sup>(5)</sup>	1.7 V ≤ V <sub>DD</sub> ≤ 3.6 V	0.45V <sub>DD</sub> +0.3 <sup>(1)</sup>	-	-	V
			0.4V <sub>DD</sub> <sup>(2)</sup>			
	BOOT0 I/O input high level voltage	1.75 V ≤ V <sub>DD</sub> ≤ 3.6 V, -40 °C ≤ T <sub>A</sub> ≤ 105 °C	0.17V <sub>DD</sub> +0.7 <sup>(1)</sup>	-	-	
		1.7 V ≤ V <sub>DD</sub> ≤ 3.6 V, 0 °C ≤ T <sub>A</sub> ≤ 105 °C				

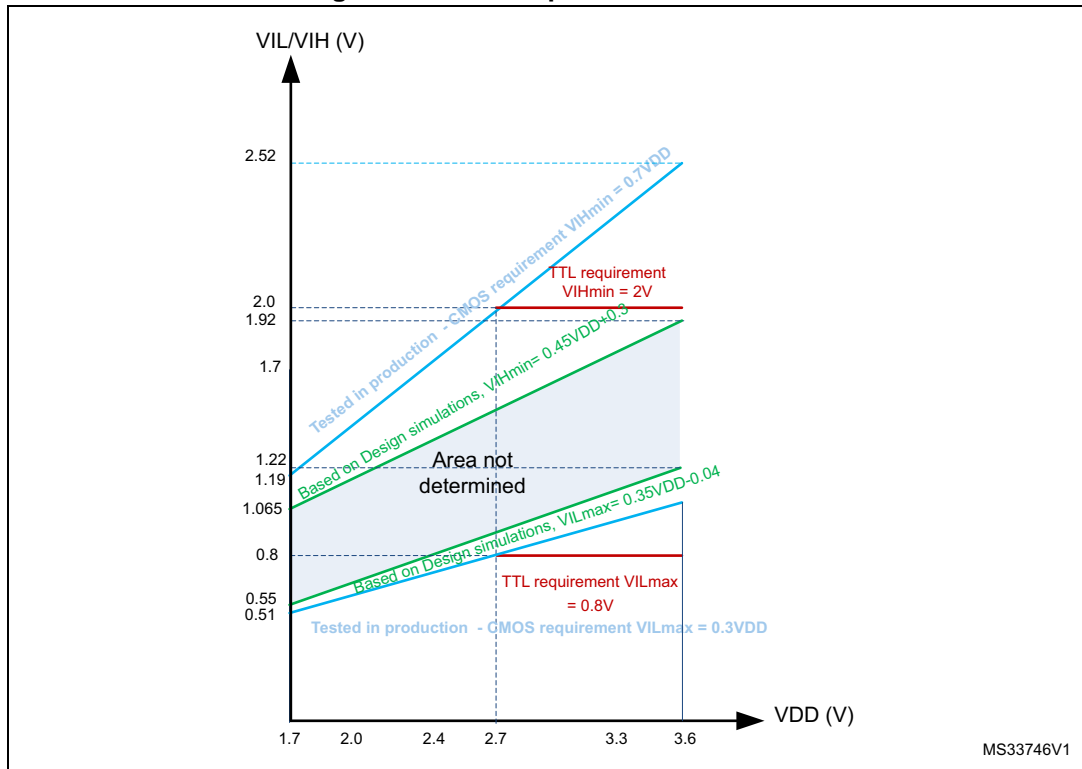
Table 54. I/O static characteristics (continued)

Symbol	Parameter		Conditions	Min	Typ	Max	Unit
V <sub>HYS</sub>	FT and NRST I/O input hysteresis		1.7 V ≤ V <sub>DD</sub> ≤ 3.6 V	-	10% V <sub>DD</sub> <sup>(3)</sup>	-	V
	BOOT0 I/O input hysteresis		1.75 V ≤ V <sub>DD</sub> ≤ 3.6 V, -40 °C ≤ T <sub>A</sub> ≤ 105 °C	-	100	-	mV
		1.7 V ≤ V <sub>DD</sub> ≤ 3.6 V, 0 °C ≤ T <sub>A</sub> ≤ 105 °C					
I <sub>lkg</sub>	I/O input leakage current <sup>(4)</sup>		V <sub>SS</sub> ≤ V <sub>IN</sub> ≤ V <sub>DD</sub>	-	-	±1	μA
	I/O FT input leakage current <sup>(5)</sup>		V <sub>IN</sub> = 5 V	-	-	3	
R <sub>PU</sub>	Weak pull-up equivalent resistor <sup>(6)</sup>	All pins except for PA10 (OTG_FS_ID)	V <sub>IN</sub> = V <sub>SS</sub>	30	40	50	kΩ
		PA10 (OTG_FS_ID)		7	10	14	
R <sub>PD</sub>	Weak pull-down equivalent resistor <sup>(7)</sup>	All pins except for PA10 (OTG_FS_ID)	V <sub>IN</sub> = V <sub>DD</sub>	30	40	50	
		PA10 (OTG_FS_ID)		7	10	14	
C <sub>IO</sub> <sup>(8)</sup>	I/O pin capacitance		-	-	5	-	pF

1. Guaranteed by design, not tested in production.
2. Guaranteed by test in production.
3. With a minimum of 200 mV.
4. Leakage could be higher than the maximum value, if negative current is injected on adjacent pins, Refer to [Table 53: I/O current injection susceptibility](#)
5. To sustain a voltage higher than VDD +0.3 V, the internal pull-up/pull-down resistors must be disabled. Leakage could be higher than the maximum value, if negative current is injected on adjacent pins. Refer to [Table 53: I/O current injection susceptibility](#)
6. Pull-up resistors are designed with a true resistance in series with a switchable PMOS. This PMOS contribution to the series resistance is minimum (~10% order).
7. Pull-down resistors are designed with a true resistance in series with a switchable NMOS. This NMOS contribution to the series resistance is minimum (~10% order).
8. Hysteresis voltage between Schmitt trigger switching levels. Guaranteed by characterization, not tested in production.

All I/Os are CMOS and TTL compliant (no software configuration required). Their characteristics cover more than the strict CMOS-technology or TTL parameters. The coverage of these requirements for FT I/Os is shown in [Figure 30](#).

Figure 30. FT I/O input characteristics



**Output driving current**

The GPIOs (general purpose input/outputs) can sink or source up to ±8 mA, and sink or source up to ±20 mA (with a relaxed VOL/VOH) except PC13, PC14 and PC15 which can sink or source up to ±3mA. When using the PC13 to PC15 GPIOs in output mode, the speed should not exceed 2 MHz with a maximum load of 30 pF.

In the user application, the number of I/O pins which can drive current must be limited to respect the absolute maximum rating specified in Section 6.2. In particular:

- The sum of the currents sourced by all the I/Os on VDD, plus the maximum Run consumption of the MCU sourced on VDD, cannot exceed the absolute maximum rating ΣI<sub>VDD</sub> (see Table 12).
- The sum of the currents sunk by all the I/Os on VSS plus the maximum Run consumption of the MCU sunk on VSS cannot exceed the absolute maximum rating ΣI<sub>VSS</sub> (see Table 12).

**Output voltage levels**

Unless otherwise specified, the parameters given in Table 55 are derived from tests performed under ambient temperature and VDD supply voltage conditions summarized in Table 14. All I/Os are CMOS and TTL compliant.

Table 55. Output voltage characteristics

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{OL}^{(1)}$	Output low level voltage for an I/O pin	CMOS port <sup>(2)</sup> $I_{IO} = +8 \text{ mA}$ $2.7 \text{ V} \leq V_{DD} \leq 3.6 \text{ V}$	-	0.4	V
$V_{OH}^{(3)}$	Output high level voltage for an I/O pin		$V_{DD}-0.4$	-	
$V_{OL}^{(1)}$	Output low level voltage for an I/O pin	TTL port <sup>(2)</sup> $I_{IO} = +8 \text{ mA}$ $2.7 \text{ V} \leq V_{DD} \leq 3.6 \text{ V}$	-	0.4	V
$V_{OH}^{(3)}$	Output high level voltage for an I/O pin		2.4	-	
$V_{OL}^{(1)}$	Output low level voltage for an I/O pin	$I_{IO} = +20 \text{ mA}$ $2.7 \text{ V} \leq V_{DD} \leq 3.6 \text{ V}$	-	$1.3^{(4)}$	V
$V_{OH}^{(3)}$	Output high level voltage for an I/O pin		$V_{DD}-1.3^{(4)}$	-	
$V_{OL}^{(1)}$	Output low level voltage for an I/O pin	$I_{IO} = +6 \text{ mA}$ $1.8 \text{ V} \leq V_{DD} \leq 3.6 \text{ V}$	-	$0.4^{(4)}$	V
$V_{OH}^{(3)}$	Output high level voltage for an I/O pin		$V_{DD}-0.4^{(4)}$	-	
$V_{OL}^{(1)}$	Output low level voltage for an I/O pin	$I_{IO} = +4 \text{ mA}$ $1.7 \text{ V} \leq V_{DD} \leq 3.6 \text{ V}$	-	$0.4^{(5)}$	V
$V_{OH}^{(3)}$	Output high level voltage for an I/O pin		$V_{DD}-0.4^{(5)}$	-	

- The  $I_{IO}$  current sunk by the device must always respect the absolute maximum rating specified in [Table 12](#). and the sum of  $I_{IO}$  (I/O ports and control pins) must not exceed  $I_{VSS}$ .
- TTL and CMOS outputs are compatible with JEDEC standards JESD36 and JESD52.
- The  $I_{IO}$  current sourced by the device must always respect the absolute maximum rating specified in [Table 12](#) and the sum of  $I_{IO}$  (I/O ports and control pins) must not exceed  $I_{VDD}$ .
- Guaranteed by characterization results, not tested in production.
- Guaranteed by design, not tested in production..

### Input/output AC characteristics

The definition and values of input/output AC characteristics are given in [Figure 31](#) and , respectively.

Unless otherwise specified, the parameters given in [Table 56](#) are derived from tests performed under the ambient temperature and  $V_{DD}$  supply voltage conditions summarized in [Table 14](#).

Table 56. I/O AC characteristics<sup>(1)(2)</sup>

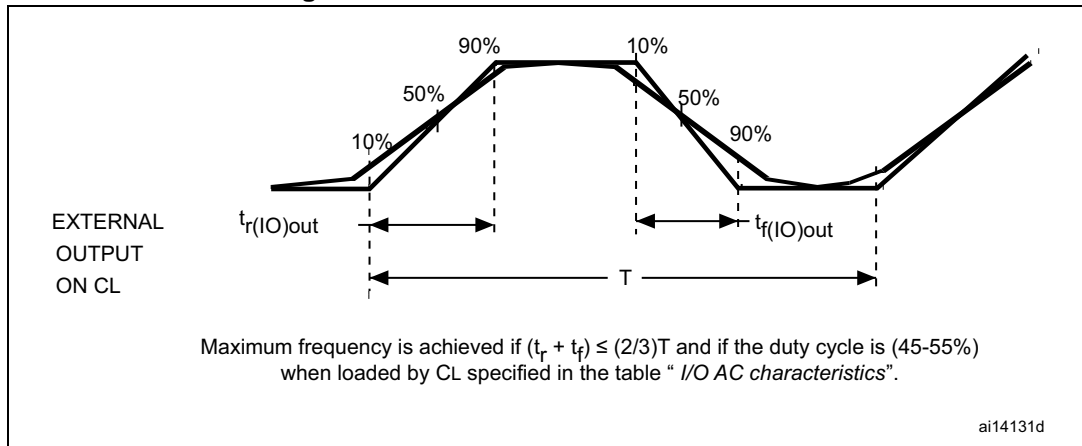
OSPEEDRy [1:0] bit value <sup>(1)</sup>	Symbol	Parameter	Conditions	Min	Typ	Max	Unit
00	$f_{\max(\text{IO})\text{out}}$	Maximum frequency <sup>(3)</sup>	$C_L = 50 \text{ pF}, V_{DD} \geq 2.70 \text{ V}$	-	-	4	MHz
			$C_L = 50 \text{ pF}, V_{DD} \geq 1.7 \text{ V}$	-	-	2	
			$C_L = 10 \text{ pF}, V_{DD} \geq 2.70 \text{ V}$	-	-	8	
			$C_L = 10 \text{ pF}, V_{DD} \geq 1.7 \text{ V}$	-	-	4	
	$t_{f(\text{IO})\text{out}}/$ $t_{r(\text{IO})\text{out}}$	Output high to low level fall time and output low to high level rise time	$C_L = 50 \text{ pF}, V_{DD} = 1.7 \text{ V to } 3.6 \text{ V}$	-	-	100	ns

Table 56. I/O AC characteristics<sup>(1)(2)</sup> (continued)

OSPEEDRy [1:0] bit value <sup>(1)</sup>	Symbol	Parameter	Conditions	Min	Typ	Max	Unit
01	f <sub>max(IO)out</sub>	Maximum frequency <sup>(3)</sup>	C <sub>L</sub> = 50 pF, V <sub>DD</sub> ≥ 2.70 V	-	-	25	MHz
			C <sub>L</sub> = 50 pF, V <sub>DD</sub> ≥ 1.7 V	-	-	12.5	
			C <sub>L</sub> = 10 pF, V <sub>DD</sub> ≥ 2.70 V	-	-	50	
			C <sub>L</sub> = 10 pF, V <sub>DD</sub> ≥ 1.7 V	-	-	20	
	t <sub>f(IO)out</sub> / t <sub>r(IO)out</sub>	Output high to low level fall time and output low to high level rise time	C <sub>L</sub> = 50 pF, V <sub>DD</sub> ≥ 2.7 V	-	-	10	ns
			C <sub>L</sub> = 50 pF, V <sub>DD</sub> ≥ 1.7 V	-	-	20	
			C <sub>L</sub> = 10 pF, V <sub>DD</sub> ≥ 2.70 V	-	-	6	
			C <sub>L</sub> = 10 pF, V <sub>DD</sub> ≥ 1.7 V	-	-	10	
10	f <sub>max(IO)out</sub>	Maximum frequency <sup>(3)</sup>	C <sub>L</sub> = 40 pF, V <sub>DD</sub> ≥ 2.70 V	-	-	50 <sup>(4)</sup>	MHz
			C <sub>L</sub> = 40 pF, V <sub>DD</sub> ≥ 1.7 V	-	-	25	
			C <sub>L</sub> = 10 pF, V <sub>DD</sub> ≥ 2.70 V	-	-	100 <sup>(4)</sup>	
			C <sub>L</sub> = 10 pF, V <sub>DD</sub> ≥ 1.7 V	-	-	50 <sup>(4)</sup>	
	t <sub>f(IO)out</sub> / t <sub>r(IO)out</sub>	Output high to low level fall time and output low to high level rise time	C <sub>L</sub> = 40 pF, V <sub>DD</sub> ≥ 2.70 V	-	-	6	ns
			C <sub>L</sub> = 40 pF, V <sub>DD</sub> ≥ 1.7 V	-	-	10	
			C <sub>L</sub> = 10 pF, V <sub>DD</sub> ≥ 2.70 V	-	-	4	
			C <sub>L</sub> = 10 pF, V <sub>DD</sub> ≥ 1.7 V	-	-	6	
11	F <sub>max(IO)out</sub>	Maximum frequency <sup>(3)</sup>	C <sub>L</sub> = 30 pF, V <sub>DD</sub> ≥ 2.70 V	-	-	100 <sup>(4)</sup>	MHz
			C <sub>L</sub> = 30 pF, V <sub>DD</sub> ≥ 1.7 V	-	-	50 <sup>(4)</sup>	
			C <sub>L</sub> = 10 pF, V <sub>DD</sub> ≥ 2.70 V	-	-	180 <sup>(4)</sup>	
			C <sub>L</sub> = 10 pF, V <sub>DD</sub> ≥ 1.7 V	-	-	100 <sup>(4)</sup>	
	t <sub>f(IO)out</sub> / t <sub>r(IO)out</sub>	Output high to low level fall time and output low to high level rise time	C <sub>L</sub> = 30 pF, V <sub>DD</sub> ≥ 2.70 V	-	-	4	ns
			C <sub>L</sub> = 30 pF, V <sub>DD</sub> ≥ 1.7 V	-	-	6	
			C <sub>L</sub> = 10 pF, V <sub>DD</sub> ≥ 2.70 V	-	-	2.5	
			C <sub>L</sub> = 10 pF, V <sub>DD</sub> ≥ 1.7 V	-	-	4	
-	t <sub>EXTIpw</sub>	Pulse width of external signals detected by the EXTI controller		10	-	-	ns

1. Guaranteed by characterization, not tested in production.
2. The I/O speed is configured using the OSPEEDRy[1:0] bits. Refer to the STM32F4xx reference manual for a description of the GPIOx\_SPEEDR GPIO port output speed register.
3. The maximum frequency is defined in [Figure 31](#).
4. For maximum frequencies above 50 MHz and V<sub>DD</sub> > 2.4 V, the compensation cell should be used.

Figure 31. I/O AC characteristics definition



### 6.3.17 NRST pin characteristics

The NRST pin input driver uses CMOS technology. It is connected to a permanent pull-up resistor,  $R_{PU}$  (see [Table 54](#)).

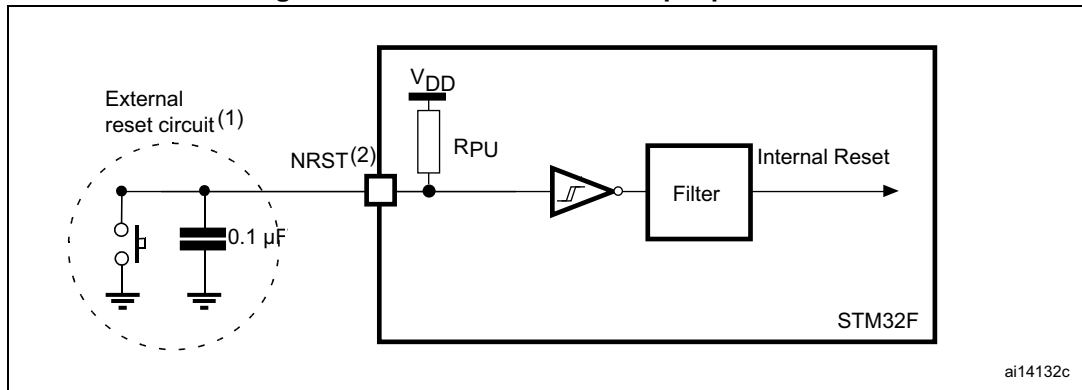
Unless otherwise specified, the parameters given in [Table 57](#) are derived from tests performed under the ambient temperature and  $V_{DD}$  supply voltage conditions summarized in [Table 14](#). Refer to [Table 54: I/O static characteristics](#) for the values of  $V_{IH}$  and  $V_{IL}$  for NRST pin.

Table 57. NRST pin characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{PU}$	Weak pull-up equivalent resistor <sup>(1)</sup>	$V_{IN} = V_{SS}$	30	40	50	k $\Omega$
$V_{F(NRST)}^{(2)}$	NRST Input filtered pulse		-	-	100	ns
$V_{NF(NRST)}^{(2)}$	NRST Input not filtered pulse	$V_{DD} > 2.7 V$	300	-	-	ns
$T_{NRST\_OUT}$	Generated reset pulse duration	Internal Reset source	20	-	-	$\mu s$

1. The pull-up is designed with a true resistance in series with a switchable PMOS. This PMOS contribution to the series resistance must be minimum (~10% order).
2. Guaranteed by design, not tested in production.

Figure 32. Recommended NRST pin protection



1. The reset network protects the device against parasitic resets.
2. The user must ensure that the level on the NRST pin can go below the  $V_{IL(NRST)}$  max level specified in [Table 57](#). Otherwise the reset is not taken into account by the device.

### 6.3.18 TIM timer characteristics

The parameters given in [Table 58](#) are guaranteed by design.

Refer to [Section 6.3.16: I/O port characteristics](#) for details on the input/output alternate function characteristics (output compare, input capture, external clock, PWM output).

Table 58. TIMx characteristics<sup>(1)(2)</sup>

Symbol	Parameter	Conditions <sup>(3)</sup>	Min	Max	Unit
$t_{res(TIM)}$	Timer resolution time	AHB/APBx prescaler=1 or 2 or 4, $f_{TIMxCLK} = 84\text{ MHz}$	1	-	$t_{TIMxCLK}$
			11.9	-	ns
		AHB/APBx prescaler > 4, $f_{TIMxCLK} = 84\text{ MHz}$	1	-	$t_{TIMxCLK}$
			11.9	-	ns
$f_{EXT}$	Timer external clock frequency on CH1 to CH4	$f_{TIMxCLK} = 84\text{ MHz}$	0	$f_{TIMxCLK}/2$	MHz
			0	42	MHz
$Res_{TIM}$	Timer resolution		-	16/32	bit
$t_{COUNTER}$	16-bit counter clock period when internal clock is selected	$f_{TIMxCLK} = 84\text{ MHz}$	0.0119	780	$\mu\text{s}$
$t_{MAX\_COUNT}$	Maximum possible count with 32-bit counter		-	$65536 \times 65536$	$t_{TIMxCLK}$
		$f_{TIMxCLK} = 84\text{ MHz}$	-	51.1	S

1. TIMx is used as a general term to refer to the TIM1 to TIM11 timers.
2. Guaranteed by design, not tested in production.
3. The maximum timer frequency on APB1 is 42 MHz and on APB2 is up to 84 MHz, by setting the TIMPRE bit in the RCC\_DCKCFGR register, if APBx prescaler is 1 or 2 or 4, then  $TIMxCLK = HCKL$ , otherwise  $TIMxCLK \geq 4 \times PCLKx$ .

### 6.3.19 Communications interfaces

#### I<sup>2</sup>C interface characteristics

The I<sup>2</sup>C interface meets the requirements of the standard I<sup>2</sup>C communication protocol with the following restrictions: the I/O pins SDA and SCL are mapped to are not “true” open-drain. When configured as open-drain, the PMOS connected between the I/O pin and VDD is disabled, but is still present.

The I<sup>2</sup>C characteristics are described in [Table 59](#). Refer also to [Section 6.3.16: I/O port characteristics](#) for more details on the input/output alternate function characteristics (SDA and SCL).

The I<sup>2</sup>C bus interface supports standard mode (up to 100 kHz) and fast mode (up to 400 kHz). The I<sup>2</sup>C bus frequency can be increased up to 1 MHz. For more details about the complete solution, please contact your local ST sales representative.

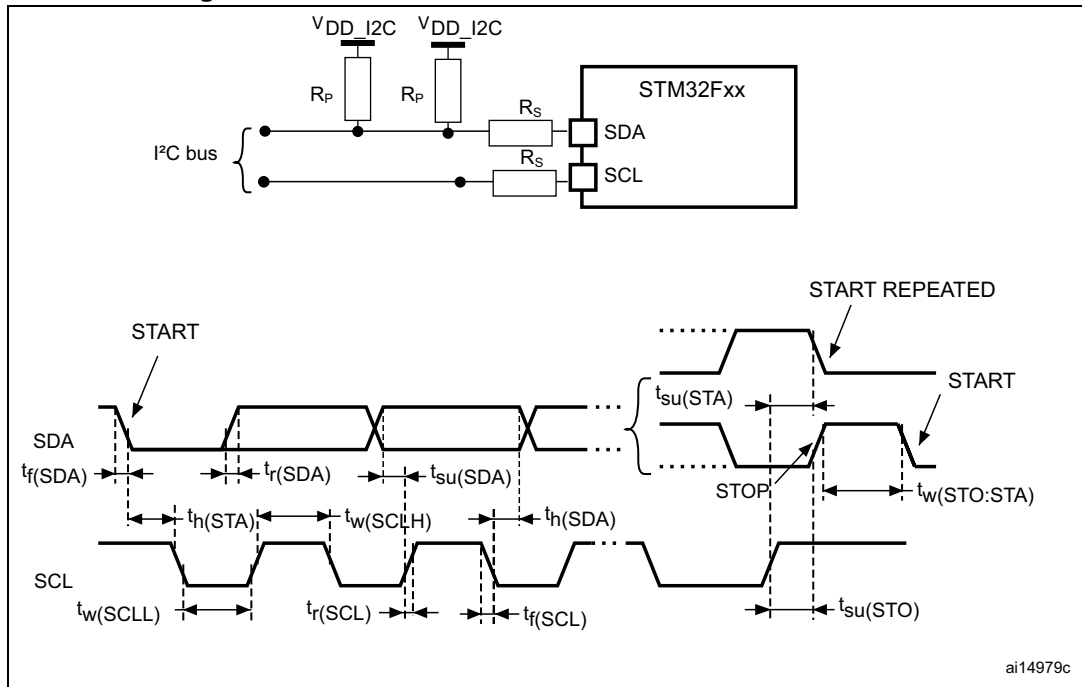
**Table 59. I<sup>2</sup>C characteristics**

Symbol	Parameter	Standard mode I <sup>2</sup> C <sup>(1)</sup>		Fast mode I <sup>2</sup> C <sup>(1)(2)</sup>		Unit
		Min	Max	Min	Max	
t <sub>w</sub> (SCLL)	SCL clock low time	4.7	-	1.3	-	μs
t <sub>w</sub> (SCLH)	SCL clock high time	4.0	-	0.6	-	
t <sub>su</sub> (SDA)	SDA setup time	250	-	100	-	ns
t <sub>h</sub> (SDA)	SDA data hold time	0	-	0	900 <sup>(3)</sup>	
t <sub>r</sub> (SDA) t <sub>r</sub> (SCL)	SDA and SCL rise time	-	1000	-	300	
t <sub>r</sub> (SDA) t <sub>r</sub> (SCL)	SDA and SCL fall time	-	300	-	300	
t <sub>h</sub> (STA)	Start condition hold time	4.0	-	0.6	-	μs
t <sub>su</sub> (STA)	Repeated Start condition setup time	4.7	-	0.6	-	
t <sub>su</sub> (STO)	Stop condition setup time	4.0	-	0.6	-	μs
t <sub>w</sub> (STO:STA)	Stop to Start condition time (bus free)	4.7	-	1.3	-	μs
C <sub>b</sub>	Capacitive load for each bus line	-	400	-	400	pF

1. Guaranteed by design, not tested in production.
2. f<sub>CLK1</sub> must be at least 2 MHz to achieve standard mode I<sup>2</sup>C frequencies. It must be at least 4 MHz to achieve fast mode I<sup>2</sup>C frequencies, and a multiple of 10 MHz to reach the 400 kHz maximum I<sup>2</sup>C fast mode clock.
3. The maximum data hold time has only to be met if the interface does not stretch the low period of SCL signal.



Figure 33. I<sup>2</sup>C bus AC waveforms and measurement circuit



1.  $R_S$  = series protection resistor.
2.  $R_P$  = external pull-up resistor.
3.  $V_{DD\_I2C}$  is the I2C bus power supply.

Table 60. SCL frequency ( $f_{PCLK1} = 42\text{ MHz}$ ,  $V_{DD} = V_{DD\_I2C} = 3.3\text{ V}$ )<sup>(1)(2)</sup>

$f_{SCL}$ (kHz)	I2C_CCR value
	$R_P = 4.7\text{ k}\Omega$
400	0x8019
300	0x8021
200	0x8032
100	0x0096
50	0x012C
20	0x02EE

1.  $R_P$  = External pull-up resistance,  $f_{SCL} = I^2C$  speed
2. For speeds around 200 kHz, the tolerance on the achieved speed is of  $\pm 5\%$ . For other speed ranges, the tolerance on the achieved speed is  $\pm 2\%$ . These variations depend on the accuracy of the external components used to design the application.

### SPI interface characteristics

Unless otherwise specified, the parameters given in [Table 61](#) for the SPI interface are derived from tests performed under the ambient temperature,  $f_{PCLKx}$  frequency and  $V_{DD}$  supply voltage conditions summarized in [Table 14](#), with the following configuration:

- Output speed is set to  $OSPEEDRy[1:0] = 10$
- Capacitive load  $C = 30$  pF
- Measurement points are done at CMOS levels:  $0.5V_{DD}$

Refer to [Section 6.3.16: I/O port characteristics](#) for more details on the input/output alternate function characteristics (NSS, SCK, MOSI, MISO for SPI).

**Table 61. SPI dynamic characteristics<sup>(1)</sup>**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$f_{SCK}$ $1/t_{c(SCK)}$	SPI clock frequency	Master mode, SPI1/4, $2.7\text{ V} < V_{DD} < 3.6\text{ V}$	-	-	42	MHz
		Slave mode, SPI1/4, $2.7\text{ V} < V_{DD} < 3.6\text{ V}$			42	
		Slave transmitter/full-duplex mode, SPI1/4, $2.7\text{ V} < V_{DD} < 3.6\text{ V}$			38 <sup>(2)</sup>	
		Master mode, SPI1/2/3/4, $1.7\text{ V} < V_{DD} < 3.6\text{ V}$			21	
		Slave mode, SPI1/2/3/4, $1.7\text{ V} < V_{DD} < 3.6\text{ V}$			21	
Duty(SCK)	Duty cycle of SPI clock frequency	Slave mode	30	50	70	%
$t_{w(SCKH)}$ $t_{w(SCKL)}$	SCK high and low time	Master mode, SPI presc = 2	$T_{PCLK}-1.5$	$T_{PCLK}$	$T_{PCLK}+1.5$	ns
$t_{su(NSS)}$	NSS setup time	Slave mode, SPI presc = 2	$4T_{PCLK}$	-	-	ns
$t_h(NSS)$	NSS hold time	Slave mode, SPI presc = 2	$2T_{PCLK}$	-	-	ns
$t_{su(MI)}$	Data input setup time	Master mode	0	-	-	ns
$t_{su(SI)}$		Slave mode	2.5	-	-	ns
$t_h(MI)$	Data input hold time	Master mode	6	-	-	ns
$t_h(SI)$		Slave mode	2.5	-	-	ns
$t_a(SO)$	Data output access time	Slave mode	9	-	20	ns
$t_{dis(SO)}$	Data output disable time	Slave mode	8	-	13	ns
$t_v(SO)$	Data output valid time	Slave mode (after enable edge), $2.7\text{ V} < V_{DD} < 3.6\text{ V}$	-	9.5	13	ns
		Slave mode (after enable edge), $1.7\text{ V} < V_{DD} < 3.6\text{ V}$	-	9.5	17	ns
$t_h(SO)$	Data output hold time	Slave mode (after enable edge), $2.7\text{ V} < V_{DD} < 3.6\text{ V}$	5.5	-	-	ns
		Slave mode (after enable edge), $1.7\text{ V} < V_{DD} < 3.6\text{ V}$	3.5	-	-	ns

Table 61. SPI dynamic characteristics<sup>(1)</sup> (continued)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$t_{v(MO)}$	Data output valid time	Master mode (after enable edge)	-	3	5	ns
$t_{h(MO)}$	Data output hold time	Master mode (after enable edge)	2	-	-	ns

1. Guaranteed by characterization, not tested in production.
2. Maximum frequency in Slave transmitter mode is determined by the sum of  $t_{v(SO)}$  and  $t_{su(MI)}$  which has to fit into SCK low or high phase preceding the SCK sampling edge. This value can be achieved when the SPI communicates with a master having  $t_{su(MI)} = 0$  while  $Duty(SCK) = 50\%$

Figure 34. SPI timing diagram - slave mode and CPHA = 0

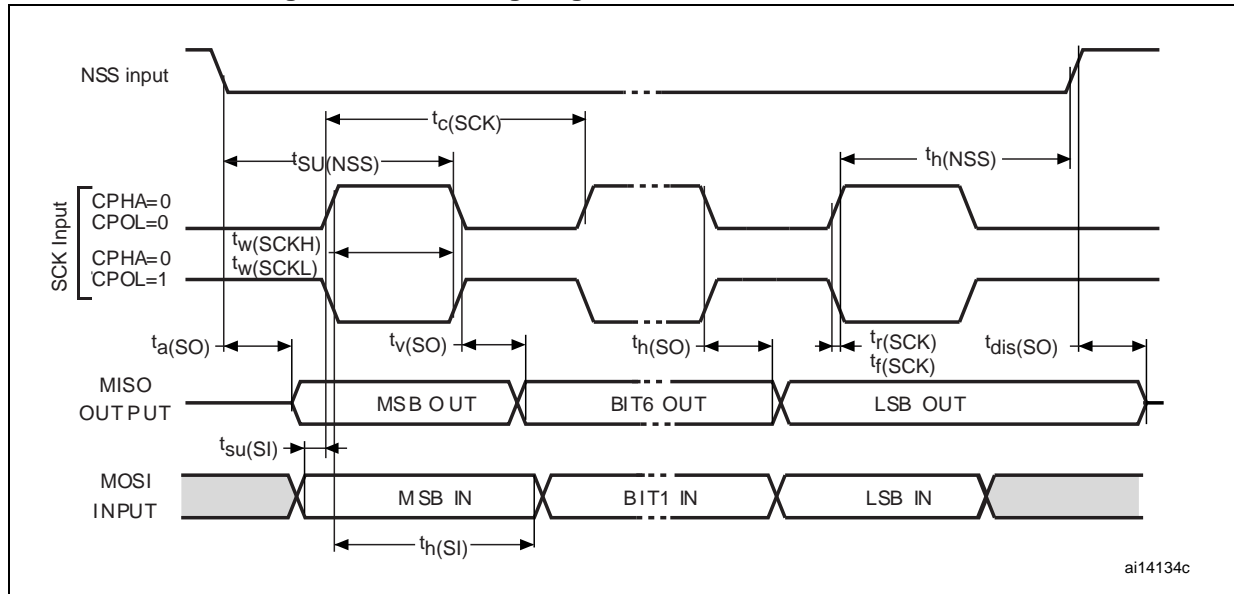


Figure 35. SPI timing diagram - slave mode and CPHA = 1<sup>(1)</sup>

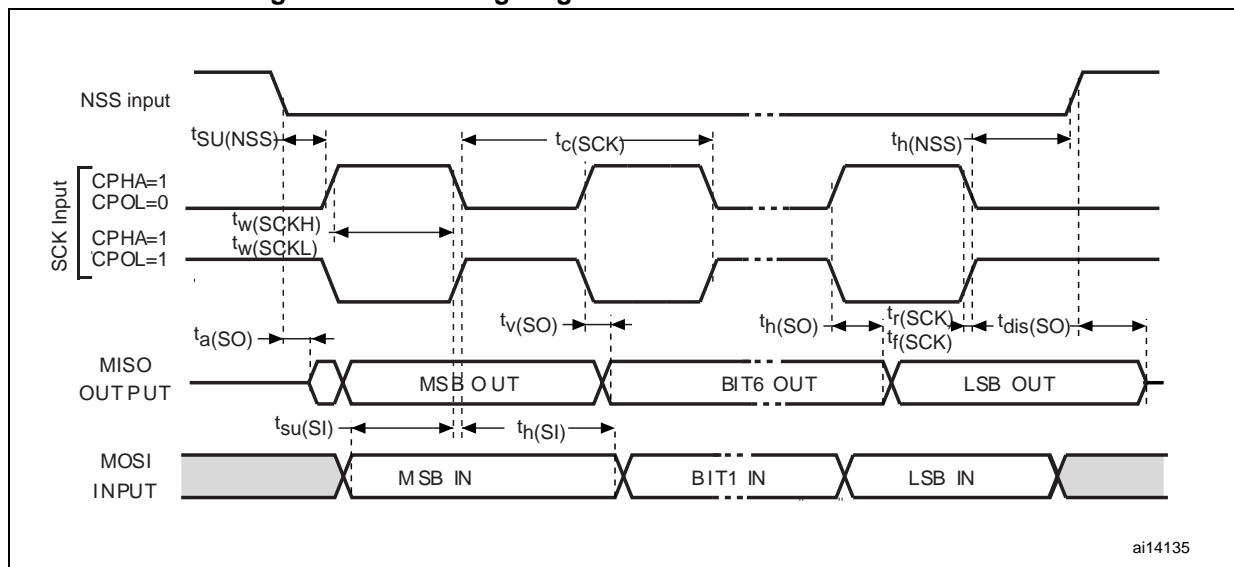
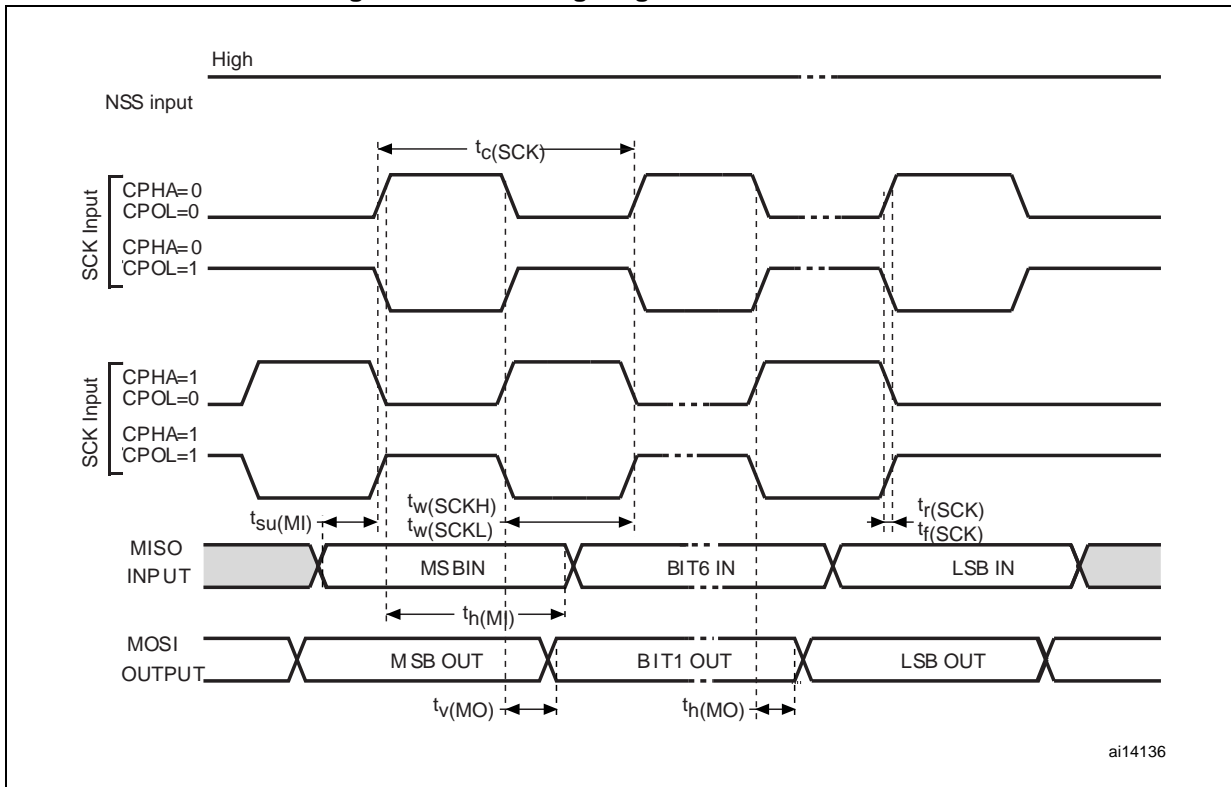


Figure 36. SPI timing diagram - master mode<sup>(1)</sup>



### I<sup>2</sup>S interface characteristics

Unless otherwise specified, the parameters given in [Table 62](#) for the I<sup>2</sup>S interface are derived from tests performed under the ambient temperature,  $f_{PCLKx}$  frequency and  $V_{DD}$  supply voltage conditions summarized in [Table 14](#), with the following configuration:

- Output speed is set to OSPEEDRy[1:0] = 10
- Capacitive load C = 30 pF
- Measurement points are done at CMOS levels: 0.5V<sub>DD</sub>

Refer to [Section 6.3.16: I/O port characteristics](#) for more details on the input/output alternate function characteristics (CK, SD, WS).

**Table 62. I<sup>2</sup>S dynamic characteristics<sup>(1)</sup>**

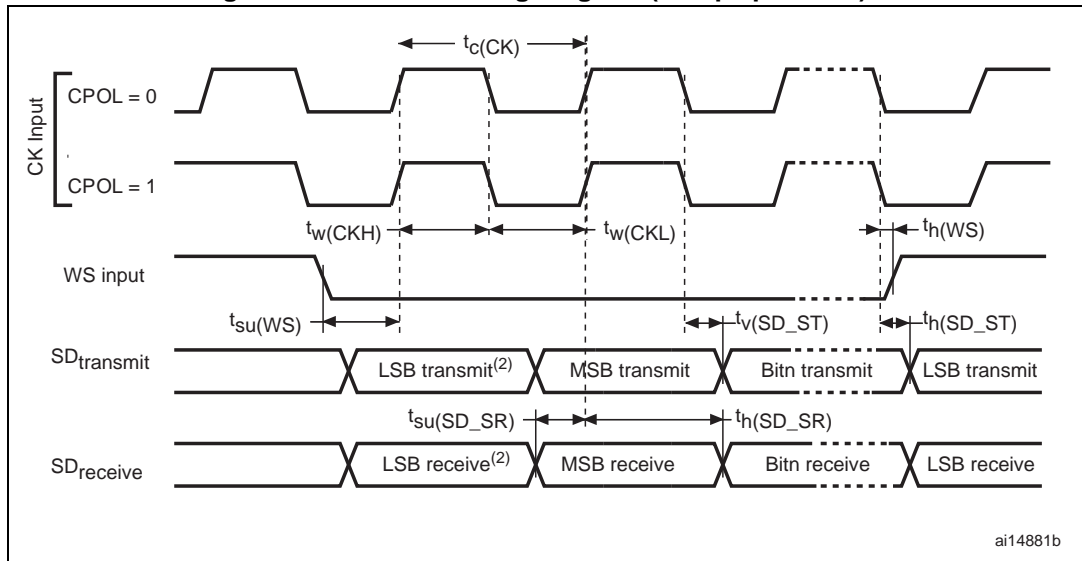
Symbol	Parameter	Conditions	Min	Max	Unit
f <sub>MCK</sub>	I2S Main clock output	-	256x8K	256xFs <sup>(2)</sup>	MHz
f <sub>CK</sub>	I2S clock frequency	Master data: 32 bits	-	64xFs	MHz
		Slave data: 32 bits	-	64xFs	
D <sub>CK</sub>	I2S clock frequency duty cycle	Slave receiver	30	70	%
t <sub>v(WS)</sub>	WS valid time	Master mode	0	6	ns
t <sub>h(WS)</sub>	WS hold time	Master mode	0	-	
t <sub>su(WS)</sub>	WS setup time	Slave mode	1	-	
t <sub>h(WS)</sub>	WS hold time	Slave mode	0	-	
t <sub>su(SD_MR)</sub>	Data input setup time	Master receiver	7.5	-	
t <sub>su(SD_SR)</sub>		Slave receiver	2	-	
t <sub>h(SD_MR)</sub>	Data input hold time	Master receiver	0	-	
t <sub>h(SD_SR)</sub>		Slave receiver	0	-	
t <sub>v(SD_ST)</sub>	Data output valid time	Slave transmitter (after enable edge)	-	27	
t <sub>h(SD_ST)</sub>		Master transmitter (after enable edge)	-	20	
t <sub>v(SD_MT)</sub>		Master transmitter (after enable edge)	-	20	
t <sub>h(SD_MT)</sub>	Data output hold time	Master transmitter (after enable edge)	2.5	-	

1. Guaranteed by characterization, not tested in production.
2. The maximum value of 256xFs is 42 MHz (APB1 maximum frequency).

**Note:** Refer to the I2S section of the reference manual for more details on the sampling frequency (F<sub>S</sub>).

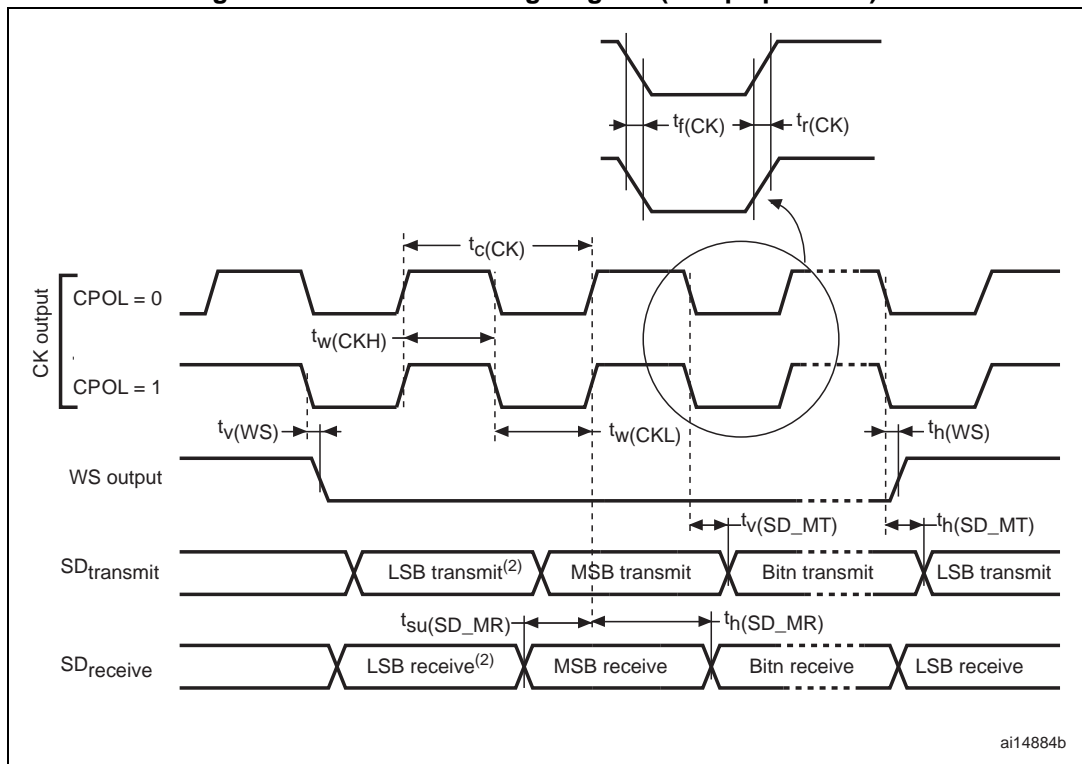
*f<sub>MCK</sub>, f<sub>CK</sub>, and D<sub>CK</sub> values reflect only the digital peripheral behavior. The values of these parameters might be slightly impacted by the source clock precision. D<sub>CK</sub> depends mainly on the value of ODD bit. The digital contribution leads to a minimum value of (I2SDIV/(2\*I2SDIV+ODD)) and a maximum value of (I2SDIV+ODD)/(2\*I2SDIV+ODD). F<sub>S</sub> maximum value is supported for each mode/condition.*

Figure 37. I<sup>2</sup>S slave timing diagram (Philips protocol)<sup>(1)</sup>



1. LSB transmit/receive of the previously transmitted byte. No LSB transmit/receive is sent before the first byte.

Figure 38. I<sup>2</sup>S master timing diagram (Philips protocol)<sup>(1)</sup>



1. LSB transmit/receive of the previously transmitted byte. No LSB transmit/receive is sent before the first byte.

**USB OTG full speed (FS) characteristics**

This interface is present in USB OTG FS controller.

**Table 63. USB OTG FS startup time**

Symbol	Parameter	Max	Unit
$t_{STARTUP}^{(1)}$	USB OTG FS transceiver startup time	1	$\mu s$

1. Guaranteed by design, not tested in production.

**Table 64. USB OTG FS DC electrical characteristics**

Symbol	Parameter	Conditions	Min. <sup>(1)</sup>	Typ.	Max. <sup>(1)</sup>	Unit	
Input levels	$V_{DD}$	USB OTG FS operating voltage	3.0 <sup>(2)</sup>	-	3.6	V	
	$V_{DI}^{(3)}$	Differential input sensitivity	I(USB_FS_DP/DM)	0.2	-	-	V
	$V_{CM}^{(3)}$	Differential common mode range	Includes $V_{DI}$ range	0.8	-	2.5	
	$V_{SE}^{(3)}$	Single ended receiver threshold		1.3	-	2.0	
Output levels	$V_{OL}$	Static output level low	$R_L$ of 1.5 k $\Omega$ to 3.6 V <sup>(4)</sup>	-	-	0.3	V
	$V_{OH}$	Static output level high	$R_L$ of 15 k $\Omega$ to $V_{SS}^{(4)}$	2.8	-	3.6	
$R_{PD}$	PA11, PA12 (USB_FS_DM/DP)	$V_{IN} = V_{DD}$	17	21	24	k $\Omega$	
	PA9 (OTG_FS_VBUS)		0.65	1.1	2.0		
$R_{PU}$	PA11, PA12 (USB_FS_DM/DP)	$V_{IN} = V_{SS}$	1.5	1.8	2.1		
	PA9 (OTG_FS_VBUS)	$V_{IN} = V_{SS}$	0.25	0.37	0.55		

1. All the voltages are measured from the local ground potential.
2. The USB OTG FS functionality is ensured down to 2.7 V but not the full USB full speed electrical characteristics which are degraded in the 2.7-to-3.0 V  $V_{DD}$  voltage range.
3. Guaranteed by design, not tested in production.
4.  $R_L$  is the load connected on the USB OTG FS drivers.

*Note:* When VBUS sensing feature is enabled, PA9 should be left at their default state (floating input), not as alternate function. A typical 200  $\mu A$  current consumption of the embedded sensing block (current to voltage conversion to determine the different sessions) can be observed on PA9 when the feature is enabled.

Figure 39. USB OTG FS timings: definition of data signal rise and fall time

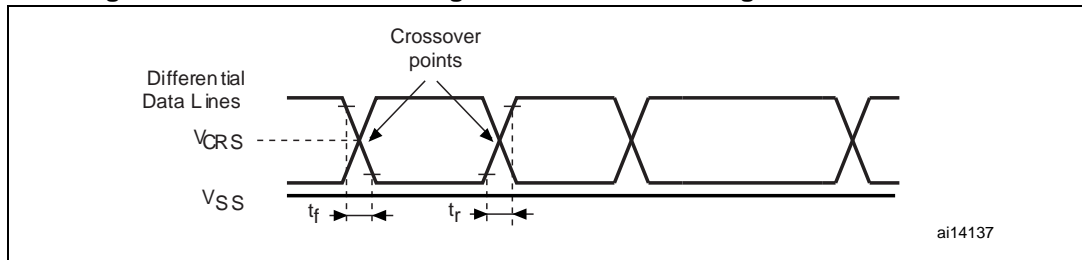


Table 65. USB OTG FS electrical characteristics<sup>(1)</sup>

Driver characteristics					
Symbol	Parameter	Conditions	Min	Max	Unit
$t_r$	Rise time <sup>(2)</sup>	$C_L = 50 \text{ pF}$	4	20	ns
$t_f$	Fall time <sup>(2)</sup>	$C_L = 50 \text{ pF}$	4	20	ns
$t_{rfm}$	Rise/ fall time matching	$t_r/t_f$	90	110	%
$V_{CRS}$	Output signal crossover voltage		1.3	2.0	V

1. Guaranteed by design, not tested in production.
2. Measured from 10% to 90% of the data signal. For more detailed informations, please refer to USB Specification - Chapter 7 (version 2.0).

### 6.3.20 12-bit ADC characteristics

Unless otherwise specified, the parameters given in [Table 66](#) are derived from tests performed under the ambient temperature,  $f_{PCLK2}$  frequency and  $V_{DDA}$  supply voltage conditions summarized in [Table 14](#).

Table 66. ADC characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{DDA}$	Power supply	$V_{DDA} - V_{REF+} < 1.2 \text{ V}$	1.7 <sup>(1)</sup>	-	3.6	V
$V_{REF+}$	Positive reference voltage		1.7 <sup>(1)</sup>	-	$V_{DDA}$	V
$f_{ADC}$	ADC clock frequency	$V_{DDA} = 1.7^{(1)} \text{ to } 2.4 \text{ V}$	0.6	15	18	MHz
		$V_{DDA} = 2.4 \text{ to } 3.6 \text{ V}$	0.6	30	36	MHz
$f_{TRIG}^{(2)}$	External trigger frequency	$f_{ADC} = 30 \text{ MHz}$ , 12-bit resolution	-	-	1764	kHz
			-	-	17	$1/f_{ADC}$
$V_{AIN}$	Conversion voltage range <sup>(3)</sup>		0 ( $V_{SSA}$ or $V_{REF-}$ tied to ground)	-	$V_{REF+}$	V
$R_{AIN}^{(2)}$	External input impedance	See <a href="#">Equation 1</a> for details	-	-	50	k $\Omega$
$R_{ADC}^{(2)(4)}$	Sampling switch resistance		-	-	6	k $\Omega$
$C_{ADC}^{(2)}$	Internal sample and hold capacitor		-	4	7	pF



Table 66. ADC characteristics (continued)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
t <sub>lat</sub> <sup>(2)</sup>	Injection trigger conversion latency	f <sub>ADC</sub> = 30 MHz	-	-	0.100	μs
			-	-	3 <sup>(5)</sup>	1/f <sub>ADC</sub>
t <sub>latr</sub> <sup>(2)</sup>	Regular trigger conversion latency	f <sub>ADC</sub> = 30 MHz	-	-	0.067	μs
			-	-	2 <sup>(5)</sup>	1/f <sub>ADC</sub>
t <sub>S</sub> <sup>(2)</sup>	Sampling time	f <sub>ADC</sub> = 30 MHz	0.100	-	16	μs
			3	-	480	1/f <sub>ADC</sub>
t <sub>STAB</sub> <sup>(2)</sup>	Power-up time		-	2	3	μs
t <sub>CONV</sub> <sup>(2)</sup>	Total conversion time (including sampling time)	f <sub>ADC</sub> = 30 MHz 12-bit resolution	0.50	-	16.40	μs
		f <sub>ADC</sub> = 30 MHz 10-bit resolution	0.43	-	16.34	μs
		f <sub>ADC</sub> = 30 MHz 8-bit resolution	0.37	-	16.27	μs
		f <sub>ADC</sub> = 30 MHz 6-bit resolution	0.30	-	16.20	μs
		9 to 492 (t <sub>S</sub> for sampling +n-bit resolution for successive approximation)				
f <sub>S</sub> <sup>(2)</sup>	Sampling rate (f <sub>ADC</sub> = 30 MHz, and t <sub>S</sub> = 3 ADC cycles)	12-bit resolution Single ADC	-	-	2	MspS
		12-bit resolution Interleave Dual ADC mode	-	-	3.75	MspS
		12-bit resolution Interleave Triple ADC mode	-	-	6	MspS
I <sub>VREF+</sub> <sup>(2)</sup>	ADC V <sub>REF</sub> DC current consumption in conversion mode		-	300	500	μA
I <sub>VDDA</sub> <sup>(2)</sup>	ADC V <sub>DDA</sub> DC current consumption in conversion mode		-	1.6	1.8	mA

1. V<sub>DDA</sub> minimum value of 1.7 V is possible with the use of an external power supply supervisor (refer to [Section 3.14.2: Internal reset OFF](#)).
2. Guaranteed by characterization, not tested in production.
3. V<sub>REF+</sub> is internally connected to V<sub>DDA</sub> and V<sub>REF-</sub> is internally connected to V<sub>SSA</sub>.
4. R<sub>ADC</sub> maximum value is given for V<sub>DD</sub>=1.7 V, and minimum value for V<sub>DD</sub>=3.3 V.
5. For external triggers, a delay of 1/f<sub>PCLK2</sub> must be added to the latency specified in [Table 66](#).

**Equation 1: R<sub>AIN</sub> max formula**

$$R_{AIN} = \frac{(k - 0,5)}{f_{ADC} \times C_{ADC} \times \ln(2^{N+2})} - R_{ADC}$$



The formula above (*Equation 1*) is used to determine the maximum external impedance allowed for an error below 1/4 of LSB. N = 12 (from 12-bit resolution) and k is the number of sampling periods defined in the ADC\_SMPR1 register.

**Table 67. ADC accuracy at  $f_{ADC} = 18 \text{ MHz}^{(1)}$**

Symbol	Parameter	Test conditions	Typ	Max <sup>(2)</sup>	Unit
ET	Total unadjusted error	$f_{ADC} = 18 \text{ MHz}$ $V_{DDA} = 1.7 \text{ to } 3.6 \text{ V}$ $V_{REF} = 1.7 \text{ to } 3.6 \text{ V}$ $V_{DDA} - V_{REF} < 1.2 \text{ V}$	±3	±4	LSB
EO	Offset error		±2	±3	
EG	Gain error		±1	±3	
ED	Differential linearity error		±1	±2	
EL	Integral linearity error		±2	±3	

1. Better performance could be achieved in restricted  $V_{DD}$ , frequency and temperature ranges.
2. Guaranteed by characterization, not tested in production.

**Table 68. ADC accuracy at  $f_{ADC} = 30 \text{ MHz}^{(1)}$**

Symbol	Parameter	Test conditions	Typ	Max <sup>(2)</sup>	Unit
ET	Total unadjusted error	$f_{ADC} = 30 \text{ MHz}$ , $R_{AIN} < 10 \text{ k}\Omega$ , $V_{DDA} = 2.4 \text{ to } 3.6 \text{ V}$ , $V_{REF} = 1.7 \text{ to } 3.6 \text{ V}$ , $V_{DDA} - V_{REF} < 1.2 \text{ V}$	±2	±5	LSB
EO	Offset error		±1.5	±2.5	
EG	Gain error		±1.5	±4	
ED	Differential linearity error		±1	±2	
EL	Integral linearity error		±1.5	±3	

1. Better performance could be achieved in restricted  $V_{DD}$ , frequency and temperature ranges.
2. Guaranteed by characterization, not tested in production.

**Table 69. ADC accuracy at  $f_{ADC} = 36 \text{ MHz}^{(1)}$**

Symbol	Parameter	Test conditions	Typ	Max <sup>(2)</sup>	Unit
ET	Total unadjusted error	$f_{ADC} = 36 \text{ MHz}$ , $V_{DDA} = 2.4 \text{ to } 3.6 \text{ V}$ , $V_{REF} = 1.7 \text{ to } 3.6 \text{ V}$ $V_{DDA} - V_{REF} < 1.2 \text{ V}$	±4	±7	LSB
EO	Offset error		±2	±3	
EG	Gain error		±3	±6	
ED	Differential linearity error		±2	±3	
EL	Integral linearity error		±3	±6	

1. Better performance could be achieved in restricted  $V_{DD}$ , frequency and temperature ranges.
2. Guaranteed by characterization, not tested in production.

**Table 70. ADC dynamic accuracy at  $f_{ADC} = 18$  MHz - limited test conditions<sup>(1)</sup>**

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
ENOB	Effective number of bits	$f_{ADC} = 18$ MHz $V_{DDA} = V_{REF+} = 1.7$ V Input Frequency = 20 KHz Temperature = 25 °C	10.3	10.4	-	bits
SINAD	Signal-to-noise and distortion ratio		64	64.2	-	dB
SNR	Signal-to-noise ratio		64	65	-	
THD	Total harmonic distortion		-67	-72	-	

1. Guaranteed by characterization, not tested in production.

**Table 71. ADC dynamic accuracy at  $f_{ADC} = 36$  MHz - limited test conditions<sup>(1)</sup>**

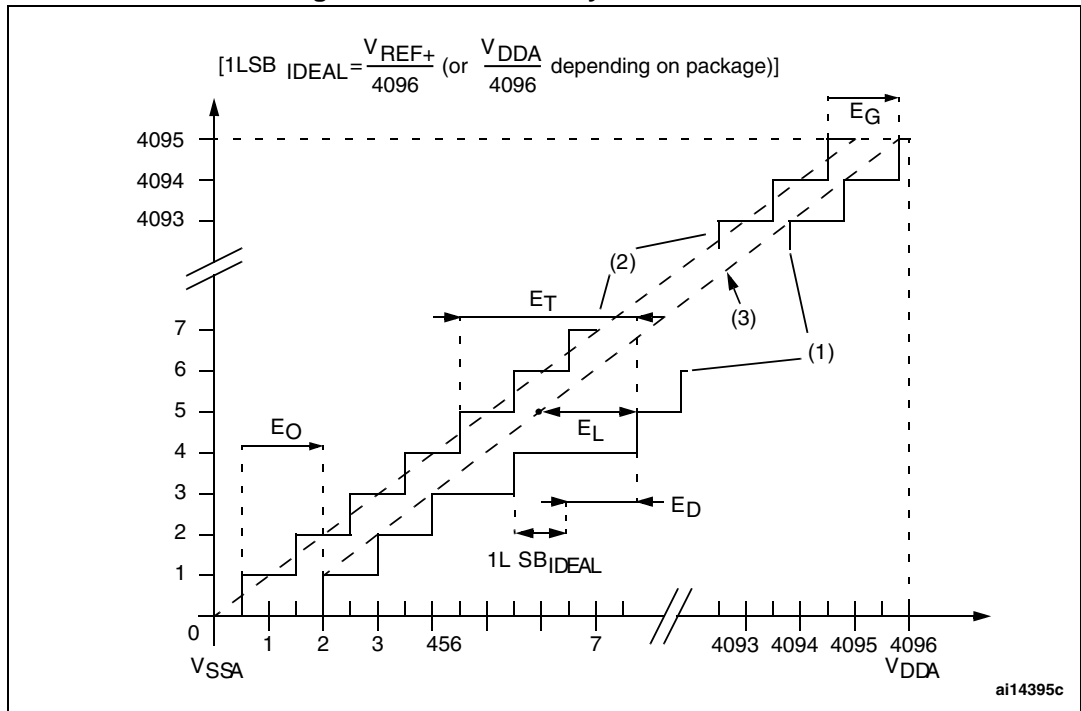
Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
ENOB	Effective number of bits	$f_{ADC} = 36$ MHz $V_{DDA} = V_{REF+} = 3.3$ V Input Frequency = 20 KHz Temperature = 25 °C	10.6	10.8	-	bits
SINAD	Signal-to noise and distortion ratio		66	67	-	dB
SNR	Signal-to noise ratio		64	68	-	
THD	Total harmonic distortion		-70	-72	-	

1. Guaranteed by characterization, not tested in production.

Note: ADC accuracy vs. negative injection current: injecting a negative current on any analog input pins should be avoided as this significantly reduces the accuracy of the conversion being performed on another analog input. It is recommended to add a Schottky diode (pin to ground) to analog pins which may potentially inject negative currents.

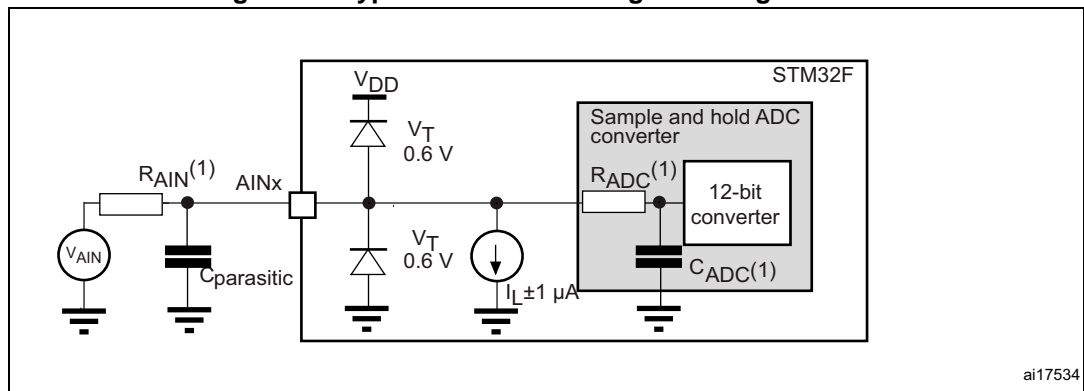
Any positive injection current within the limits specified for  $I_{INJ(PIN)}$  and  $\Sigma I_{INJ(PIN)}$  in [Section 6.3.16](#) does not affect the ADC accuracy.

Figure 40. ADC accuracy characteristics



1. See also [Table 68](#).
2. Example of an actual transfer curve.
3. Ideal transfer curve.
4. End point correlation line.
5.  $E_T$  = Total Unadjusted Error: maximum deviation between the actual and the ideal transfer curves.  
 $E_O$  = Offset Error: deviation between the first actual transition and the first ideal one.  
 $E_G$  = Gain Error: deviation between the last ideal transition and the last actual one.  
 $E_D$  = Differential Linearity Error: maximum deviation between actual steps and the ideal one.  
 $E_L$  = Integral Linearity Error: maximum deviation between any actual transition and the end point correlation line.

Figure 41. Typical connection diagram using the ADC

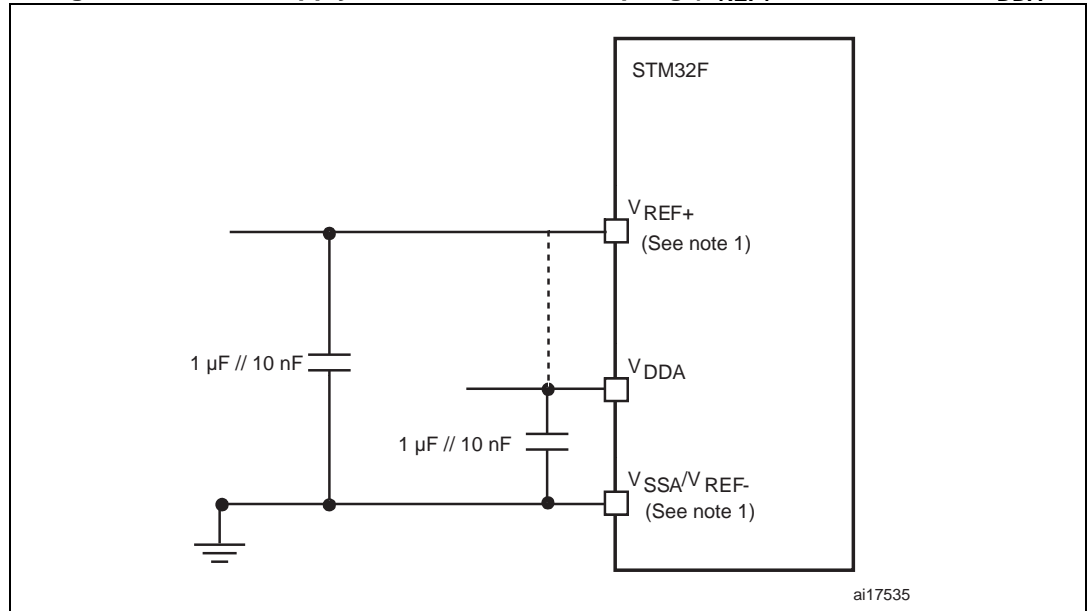


1. Refer to [Table 66](#) for the values of  $R_{AIN}$ ,  $R_{ADC}$  and  $C_{ADC}$ .
2.  $C_{parasitic}$  represents the capacitance of the PCB (dependent on soldering and PCB layout quality) plus the pad capacitance (roughly 5 pF). A high  $C_{parasitic}$  value downgrades conversion accuracy. To remedy this,  $f_{ADC}$  should be reduced.

**General PCB design guidelines**

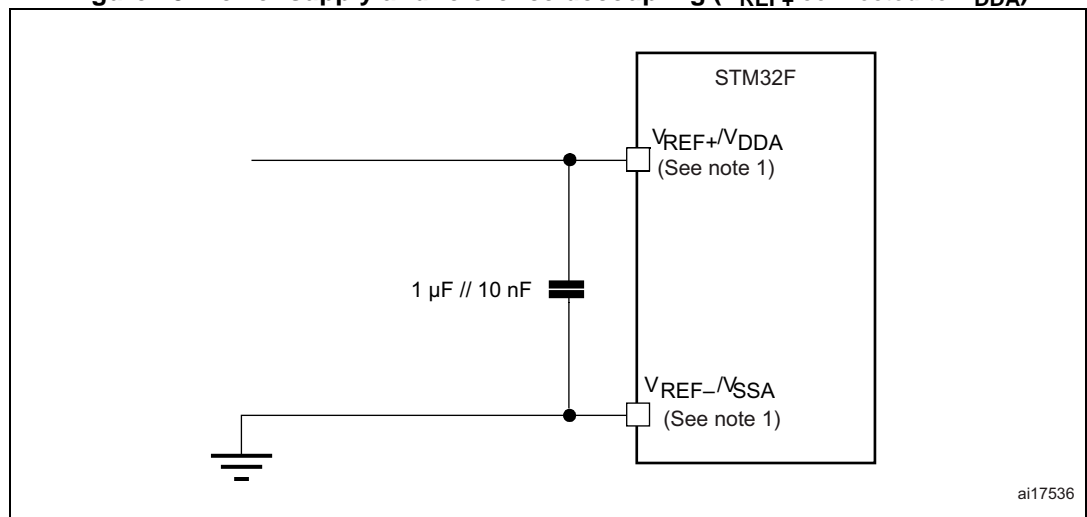
Power supply decoupling should be performed as shown in [Figure 42](#) or [Figure 43](#), depending on whether  $V_{REF+}$  is connected to  $V_{DDA}$  or not. The 10 nF capacitors should be ceramic (good quality). They should be placed them as close as possible to the chip.

**Figure 42. Power supply and reference decoupling ( $V_{REF+}$  not connected to  $V_{DDA}$ )**



1.  $V_{REF+}$  and  $V_{REF-}$  inputs are both available on UFBGA100.  $V_{REF+}$  is also available on LQFP100. When  $V_{REF+}$  and  $V_{REF-}$  are not available, they are internally connected to  $V_{DDA}$  and  $V_{SSA}$ .

**Figure 43. Power supply and reference decoupling ( $V_{REF+}$  connected to  $V_{DDA}$ )**



1.  $V_{REF+}$  and  $V_{REF-}$  inputs are both available on UFBGA100.  $V_{REF+}$  is also available on LQFP100. When  $V_{REF+}$  and  $V_{REF-}$  are not available, they are internally connected to  $V_{DDA}$  and  $V_{SSA}$ .

### 6.3.21 Temperature sensor characteristics

**Table 72. Temperature sensor characteristics**

Symbol	Parameter	Min	Typ	Max	Unit
$T_L^{(1)}$	$V_{SENSE}$ linearity with temperature	-	$\pm 1$	$\pm 2$	$^{\circ}\text{C}$
Avg_Slope <sup>(1)</sup>	Average slope	-	2.5	-	mV/ $^{\circ}\text{C}$
$V_{25}^{(1)}$	Voltage at 25 $^{\circ}\text{C}$	-	0.76	-	V
$t_{START}^{(2)}$	Startup time	-	6	10	$\mu\text{s}$
$T_{S\_temp}^{(2)}$	ADC sampling time when reading the temperature (1 $^{\circ}\text{C}$ accuracy)	10	-	-	$\mu\text{s}$

1. Guaranteed by characterization, not tested in production.
2. Guaranteed by design, not tested in production.

**Table 73. Temperature sensor calibration values**

Symbol	Parameter	Memory address
TS_CAL1	TS ADC raw data acquired at temperature of 30 $^{\circ}\text{C}$ , $V_{DDA} = 3.3\text{ V}$	0x1FFF 7A2C - 0x1FFF 7A2D
TS_CAL2	TS ADC raw data acquired at temperature of 110 $^{\circ}\text{C}$ , $V_{DDA} = 3.3\text{ V}$	0x1FFF 7A2E - 0x1FFF 7A2F

### 6.3.22 $V_{BAT}$ monitoring characteristics

**Table 74.  $V_{BAT}$  monitoring characteristics**

Symbol	Parameter	Min	Typ	Max	Unit
R	Resistor bridge for $V_{BAT}$	-	50	-	K $\Omega$
Q	Ratio on $V_{BAT}$ measurement	-	4	-	
$E_r^{(1)}$	Error on Q	-1	-	+1	%
$T_{S\_vbat}^{(2)(2)}$	ADC sampling time when reading the $V_{BAT}$ 1 mV accuracy	5	-	-	$\mu\text{s}$

1. Guaranteed by design, not tested in production.
2. Shortest sampling time can be determined in the application by multiple iterations.

### 6.3.23 Embedded reference voltage

The parameters given in [Table 75](#) are derived from tests performed under ambient temperature and  $V_{DD}$  supply voltage conditions summarized in [Table 14](#).

**Table 75. Embedded internal reference voltage**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{REFINT}$	Internal reference voltage	$-40\text{ }^{\circ}\text{C} < T_A < +105\text{ }^{\circ}\text{C}$	1.18	1.21	1.24	V
$T_{S\_vrefint}^{(1)}$	ADC sampling time when reading the internal reference voltage	-	10	-	-	$\mu\text{s}$
$V_{RERINT\_s}^{(2)}$	Internal reference voltage spread over the temperature range	$V_{DD} = 3\text{V} \pm 10\text{mV}$	-	3	5	mV

**Table 75. Embedded internal reference voltage (continued)**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$T_{Coeff}^{(2)}$	Temperature coefficient	-	-	30	50	ppm/°C
$t_{START}^{(2)}$	Startup time	-	-	6	10	µs

1. Shortest sampling time can be determined in the application by multiple iterations.
2. Guaranteed by design, not tested in production

**Table 76. Internal reference voltage calibration values**

Symbol	Parameter	Memory address
$V_{REFIN\_CAL}$	Raw data acquired at temperature of 30 °C $V_{DDA} = 3.3$ V	0x1FFF 7A2A - 0x1FFF 7A2B

**6.3.24 SD/SDIO MMC card host interface (SDIO) characteristics**

Unless otherwise specified, the parameters given in [Table 77](#) for the SDIO/MMC interface are derived from tests performed under the ambient temperature,  $f_{PCLK2}$  frequency and  $V_{DD}$  supply voltage conditions summarized in [Table 14](#), with the following configuration:

- Output speed is set to  $OSPEEDRy[1:0] = 10$
- Capacitive load  $C = 30$  pF
- Measurement points are done at CMOS levels:  $0.5V_{DD}$

Refer to [Section 6.3.16: I/O port characteristics](#) for more details on the input/output characteristics.

**Figure 44. SDIO high-speed mode**

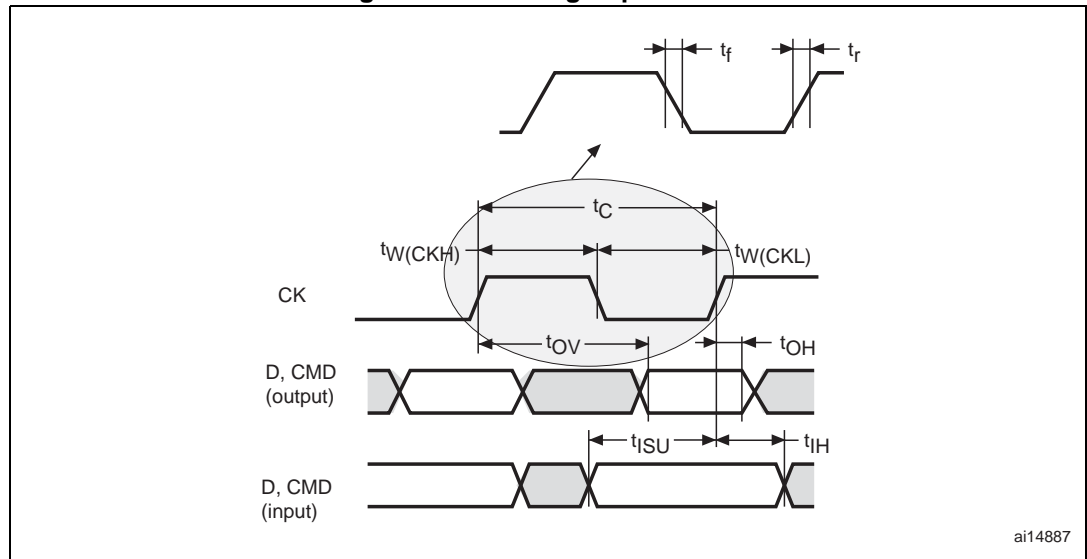


Figure 45. SD default mode

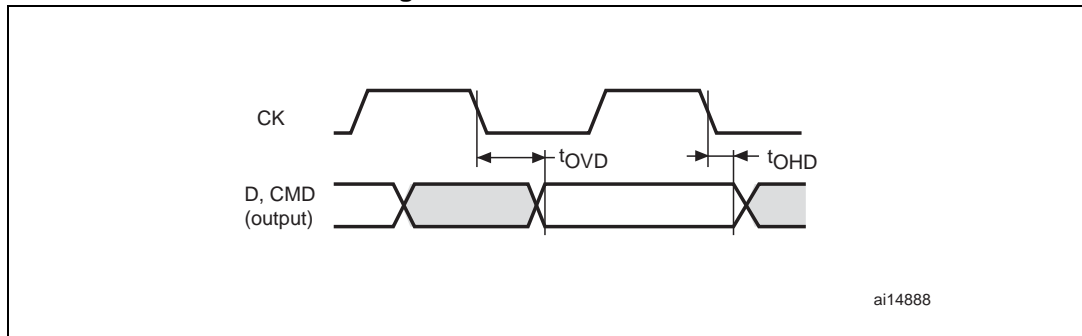


Table 77. Dynamic characteristics: SD / MMC characteristics<sup>(1)(2)</sup>

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f <sub>PP</sub>	Clock frequency in data transfer mode		0	-	48	MHz
-	SDIO_CK/fPCLK2 frequency ratio		-	-	8/3	-
t <sub>W(CKL)</sub>	Clock low time	f <sub>pp</sub> = 48MHz	8.5	9	-	ns
t <sub>W(CKH)</sub>	Clock high time	f <sub>pp</sub> = 48MHz	8.3	10	-	
<b>CMD, D inputs (referenced to CK) in MMC and SD HS mode</b>						
t <sub>ISU</sub>	Input setup time HS	f <sub>pp</sub> = 48MHz	3.5	-	-	ns
t <sub>IH</sub>	Input hold time HS	f <sub>pp</sub> = 48MHz	0	-	-	
<b>CMD, D outputs (referenced to CK) in MMC and SD HS mode</b>						
t <sub>OV</sub>	Output valid time HS	f <sub>pp</sub> = 48MHz	-	4.5	7	ns
t <sub>OH</sub>	Output hold time HS	f <sub>pp</sub> = 48MHz	3	-	-	
<b>CMD, D inputs (referenced to CK) in SD default mode</b>						
t <sub>ISUD</sub>	Input setup time SD	f <sub>pp</sub> = 24MHz	1.5	-	-	ns
t <sub>IHD</sub>	Input hold time SD	f <sub>pp</sub> = 24MHz	0.5	-	-	
<b>CMD, D outputs (referenced to CK) in SD default mode</b>						
t <sub>OVD</sub>	Output valid default time SD	f <sub>pp</sub> = 24MHz	-	4.5	6.5	ns
t <sub>OHD</sub>	Output hold default time SD	f <sub>pp</sub> = 24MHz	3.5	-	-	

1. Data based on characterization results, not tested in production.

2. V<sub>DD</sub> = 2.7 to 3.6 V.

### 6.3.25 RTC characteristics

Table 78. RTC characteristics

Symbol	Parameter	Conditions	Min	Max
-	f <sub>PCLK1</sub> /RTCCLK frequency ratio	Any read/write operation from/to an RTC register	4	-



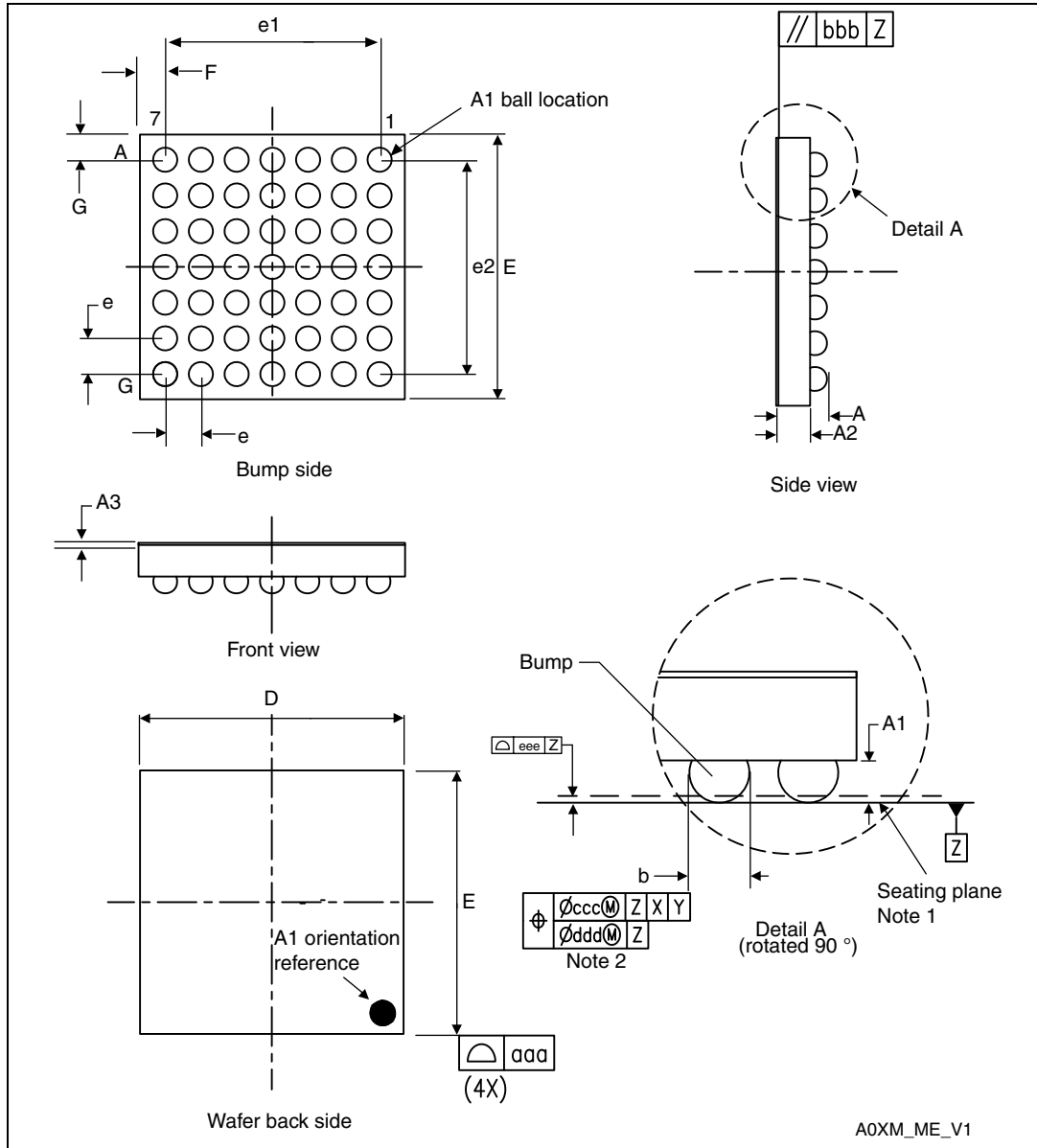
## 7 Package characteristics

### 7.1 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK<sup>®</sup> is an ST trademark.

7.1.1 WLCSP49, 3.06 x 3.06 mm, 0.4 mm pitch wafer level chip size package

Figure 46. WLCSP49 wafer level chip size package outline



1. Drawing is not to scale.

Table 79. STM32F401xCE WLCSP49 wafer level chip size package mechanical data

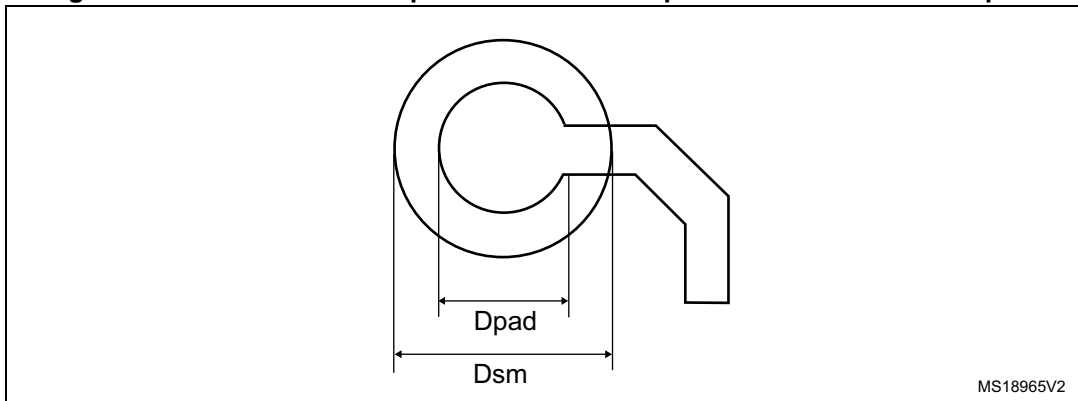
Symbol	millimeters			inches <sup>(1)</sup>		
	Min	Typ	Max	Min	Typ	Max
A	0.525	0.555	0.585	0.0207	0.0219	0.0230
A1	-	0.175	-	-	0.0069	-

**Table 79. STM32F401xCE WLCSP49 wafer level chip size package mechanical data**

Symbol	millimeters			inches <sup>(1)</sup>		
	Min	Typ	Max	Min	Typ	Max
A2	-	0.380	-	-	0.0150	-
A3 <sup>(2)</sup>	-	0.025	-	-	0.0010	-
b <sup>(3)</sup>	0.220	0.250	0.280	0.0087	0.0098	0.0110
D	2.994	3.029	3.064	0.1179	0.1193	0.1206
E	2.994	3.029	3.064	0.1179	0.1193	0.1206
e	-	0.400	-	-	0.0157	-
e1	-	2.400	-	-	0.0945	-
e2	-	2.400	-	-	0.0945	-
F	-	0.3145	-	-	0.0124	-
G	-	0.3145	-	-	0.0124	-
aaa	-	0.100	-	-	0.0039	-
bbb	-	0.100	-	-	0.0039	-
ccc	-	0.100	-	-	0.0039	-
ddd	-	0.050	-	-	0.0020	-
eee	-	0.050	-	-	0.0020	-

1. Values in inches are converted from mm and rounded to 4 decimal digits.
2. Back side coating
3. Dimension is measured at the maximum bump diameter parallel to primary datum Z.

**Figure 47. WLCSP49 0.4 mm pitch wafer level chip size recommended footprint**

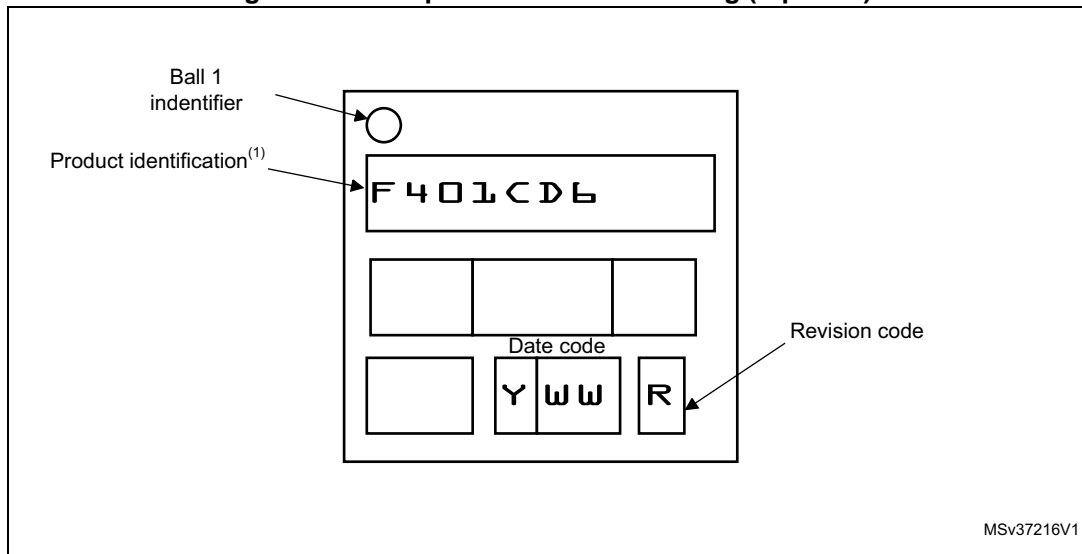


**Table 80. WLCSP49 recommended PCB design rules (0.4 mm pitch)**

Dimension	Recommended values
Pitch	0.4 mm
Dpad	260 μm max. (circular) 220 μm recommended
Dsm	300 μm min. (for 260 μm diameter pad)
PCB pad design	Non-solder mask defined via underbump allowed

**Device marking**

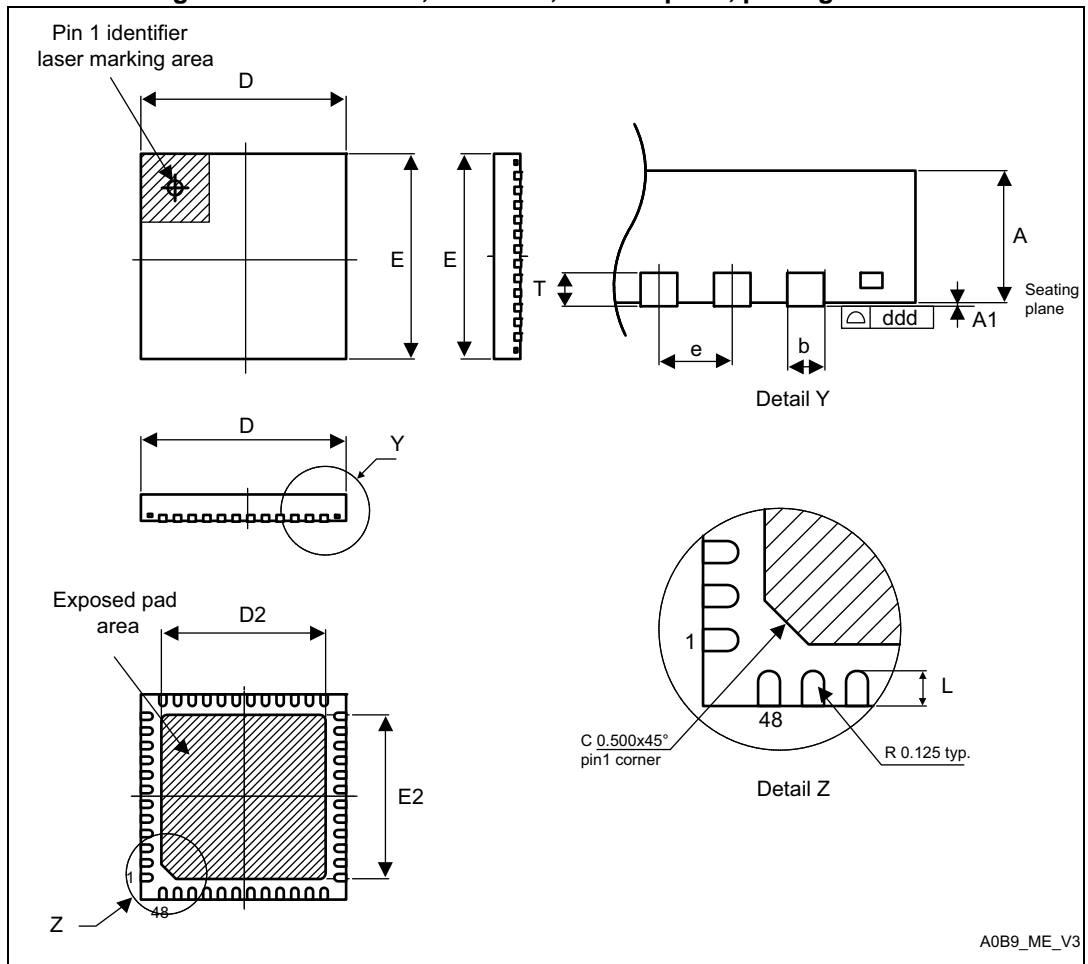
**Figure 48. Example of WLCSP49 marking (top view)**



1. Parts marked as “ES”, “E” or accompanied by an Engineering Sample notification letter, are not yet qualified and therefore not yet ready to be used in production and any consequences deriving from such usage will not be at ST charge. In no event, ST will be liable for any customer usage of these engineering samples in production. ST Quality has to be contacted prior to any decision to use these Engineering samples to run qualification activity.

7.1.2 UFQFPN48, 7 x 7 mm, 0.5 mm pitch package

Figure 49. UFQFPN48, 7 x 7 mm, 0.5 mm pitch, package outline



1. Drawing is not to scale.
2. All leads/pads should also be soldered to the PCB to improve the lead/pad solder joint life.
3. There is an exposed die pad on the underside of the UFQFPN package. It is recommended to connect and solder this back-side pad to PCB ground.

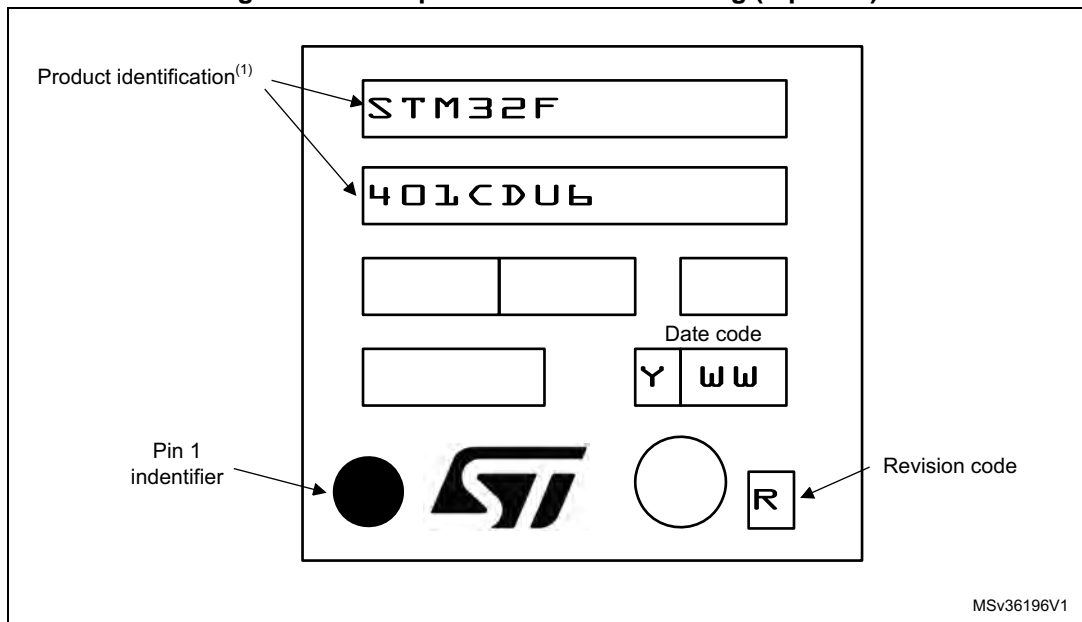
Table 81. UFQFPN48, 7 x 7 mm, 0.5 mm pitch, package mechanical data

Symbol	millimeters			inches <sup>(1)</sup>		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.500	0.550	0.600	0.0197	0.0217	0.0236
A1	0.000	0.020	0.050	0.0000	0.0008	0.0020
D	6.900	7.000	7.100	0.2717	0.2756	0.2795
E	6.900	7.000	7.100	0.2717	0.2756	0.2795
D2	5.500	5.600	5.700	0.2165	0.2205	0.2244
E2	5.500	5.600	5.700	0.2165	0.2205	0.2244
L	0.300	0.400	0.500	0.0118	0.0157	0.0197



Device marking

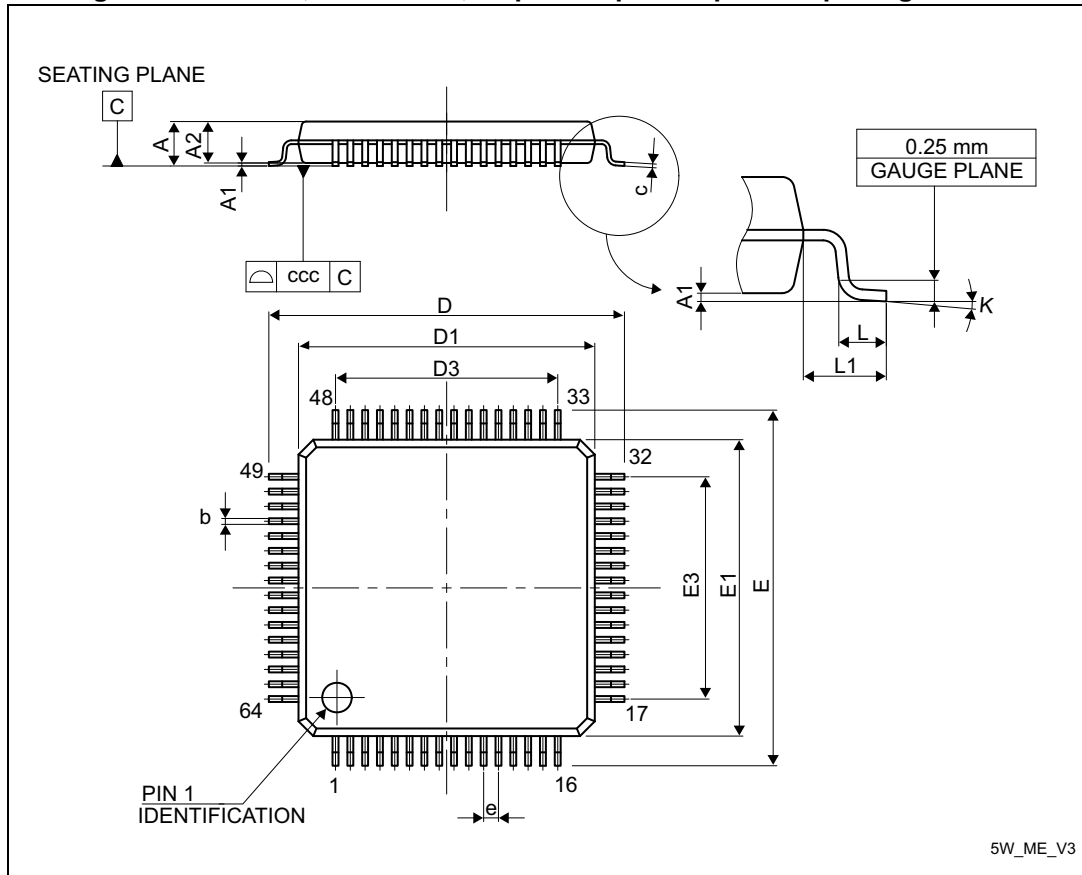
Figure 51. Example of UFQFPN48 marking (top view)



1. Parts marked as "ES", "E" or accompanied by an Engineering Sample notification letter, are not yet qualified and therefore not yet ready to be used in production and any consequences deriving from such usage will not be at ST charge. In no event, ST will be liable for any customer usage of these engineering samples in production. ST Quality has to be contacted prior to any decision to use these Engineering samples to run qualification activity.

7.1.3 LQFP64, 10 x 10 mm, 64-pin low-profile quad flat package

Figure 52. LQFP64, 10 x 10 mm, 64-pin low-profile quad flat package outline



1. Drawing is not to scale.

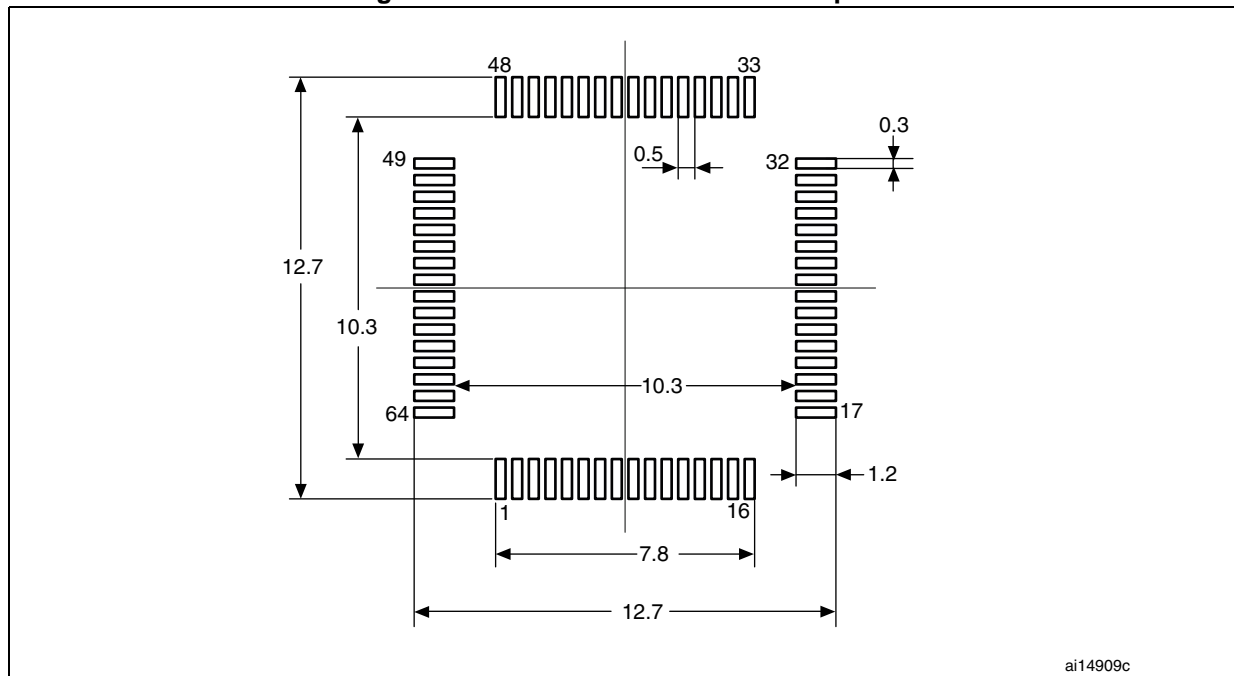


Table 82. LQFP64, 10 x 10 mm, 64-pin low-profile quad flat package mechanical data

Symbol	millimeters			inches <sup>(1)</sup>		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	-	-	1.60	-	-	0.0630
A1	0.05	-	0.15	0.0020	-	0.0059
A2	1.35	1.40	1.45	0.0531	0.0551	0.0571
b	0.17	0.22	0.27	0.0067	0.0087	0.0106
c	0.09	-	0.20	0.0035	-	0.0079
D	-	12.00	-	-	0.4724	-
D1	-	10.00	-	-	0.3937	-
E	-	12.00	-	-	0.4724	-
E1	-	10.00	-	-	0.3937	-
e	-	0.50	-	-	0.0197	-
K	0°	3.5°	7°	0°	3.5°	7°
L	0.45	0.60	0.75	0.0177	0.0236	0.0295
L1	-	1.00	-	-	0.0394	-
N	<b>Number of pins</b>					
	64					

1. Values in inches are converted from mm and rounded to 4 decimal digits.

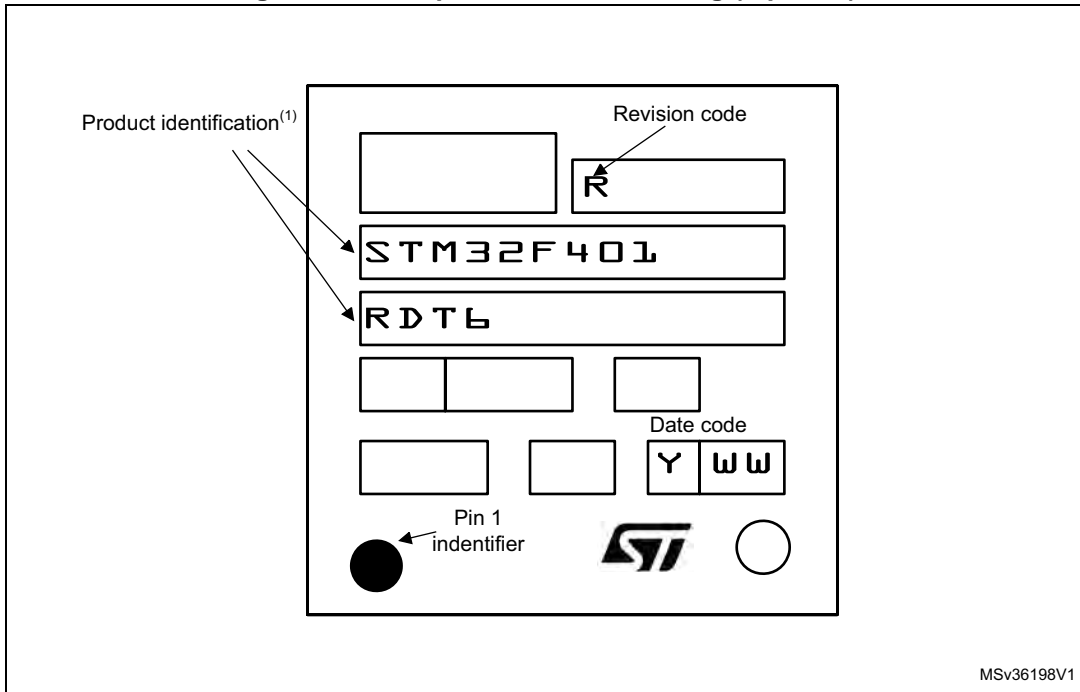
Figure 53. LQFP64 recommended footprint



1. Dimensions are in millimeters.

Device marking

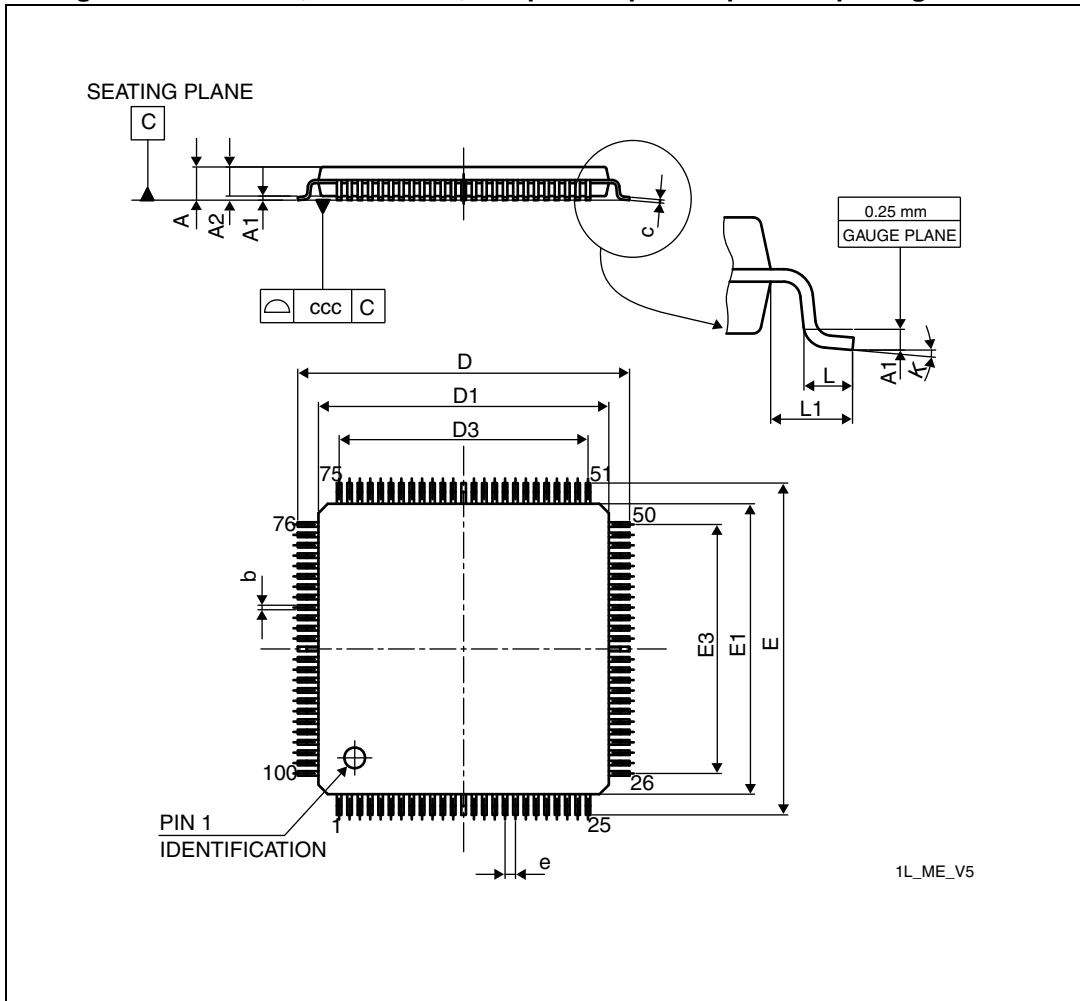
Figure 54. Example of LQFP64 marking (top view)



1. Parts marked as “ES”, “E” or accompanied by an Engineering Sample notification letter, are not yet qualified and therefore not yet ready to be used in production and any consequences deriving from such usage will not be at ST charge. In no event, ST will be liable for any customer usage of these engineering samples in production. ST Quality has to be contacted prior to any decision to use these Engineering samples to run qualification activity.

7.1.4 LQFP100, 14 x 14 mm, 100-pin low-profile quad flat package

Figure 55. LQFP100, 14 x 14 mm, 100-pin low-profile quad flat package outline



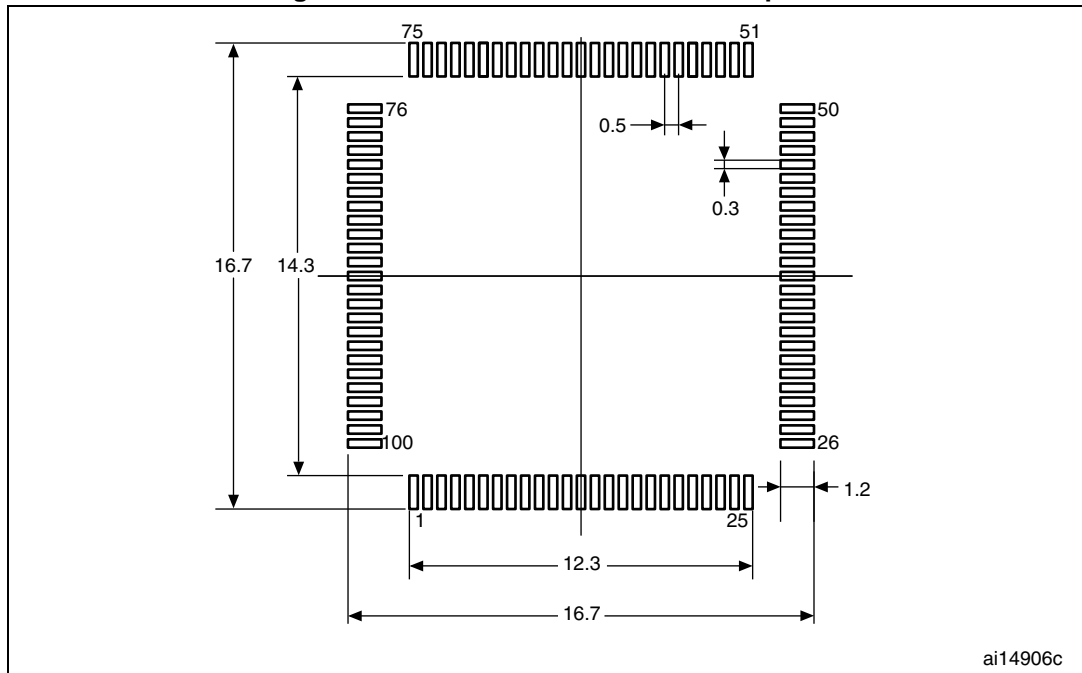
1. Drawing is not to scale.

Table 83. LQPF100, 14 x 14 mm, 100-pin low-profile quad flat package mechanical data

Symbol	millimeters			inches <sup>(1)</sup>		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	-	-	1.6	-	-	0.063
A1	0.05	-	0.15	0.002	-	0.0059
A2	1.35	1.4	1.45	0.0531	0.0551	0.0571
b	0.17	0.22	0.27	0.0067	0.0087	0.0106
c	0.09	-	0.2	0.0035	-	0.0079
D	15.8	16	16.2	0.622	0.6299	0.6378
D1	13.8	14	14.2	0.5433	0.5512	0.5591
D3	-	12	-	-	0.4724	-
E	15.8	16	16.2	0.622	0.6299	0.6378
E1	13.8	14	14.2	0.5433	0.5512	0.5591
E3	-	12	-	-	0.4724	-
e	-	0.5	-	-	0.0197	-
L	0.45	0.6	0.75	0.0177	0.0236	0.0295
L1	-	1	-	-	0.0394	-
K	0.0°	3.5°	7.0°	0.0°	3.5°	7.0°
ccc	0.08			0.0031		

1. Values in inches are converted from mm and rounded to 4 decimal digits.

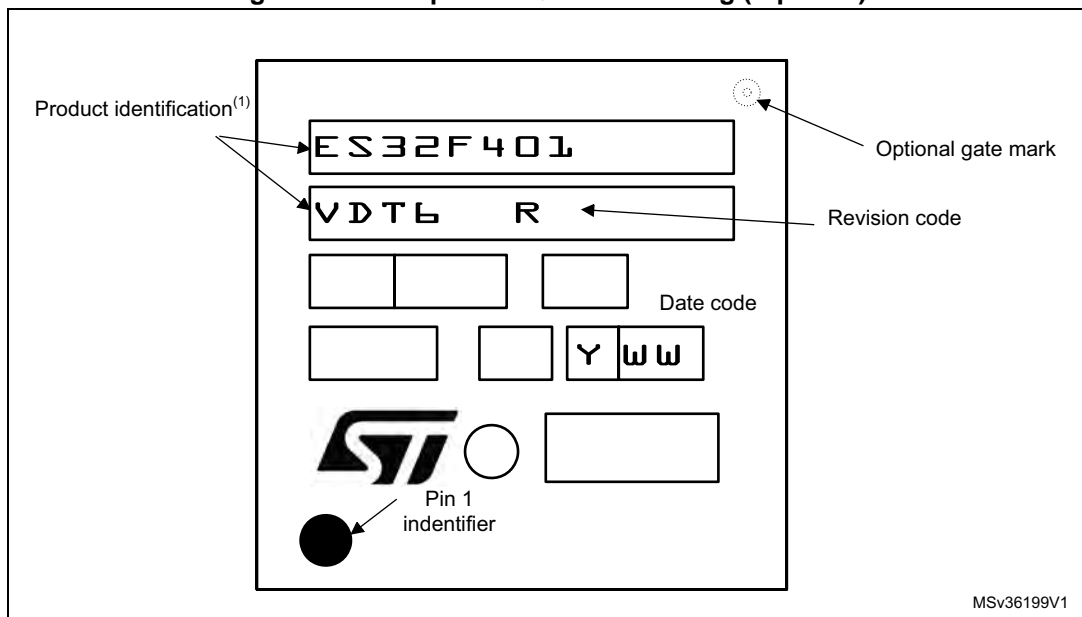
Figure 56. LQFP100 recommended footprint



1. Dimensions are in millimeters.

Device marking

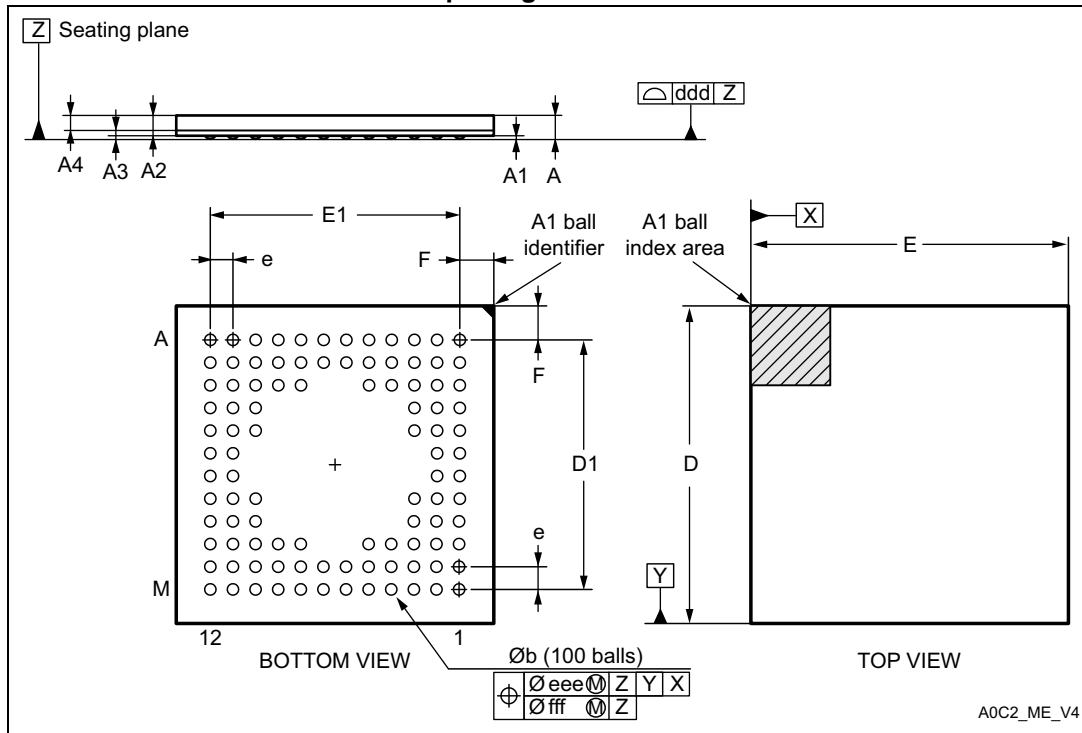
Figure 57. Example of LQPF100 marking (top view)



1. Parts marked as “ES”, “E” or accompanied by an Engineering Sample notification letter, are not yet qualified and therefore not yet ready to be used in production and any consequences deriving from such usage will not be at ST charge. In no event, ST will be liable for any customer usage of these engineering samples in production. ST Quality has to be contacted prior to any decision to use these Engineering samples to run qualification activity.

7.1.5 UFBGA100, 7 x 7 mm, 0.5 mm pitch package

Figure 58. UFBGA100, 7 x 7 mm, 0.50 mm pitch, ultra fine pitch ball grid array package outline



1. Drawing is not to scale.

Table 84. UFBGA100, 7 x 7 mm, 0.50 mm pitch, ultra fine pitch ball grid array package mechanical data

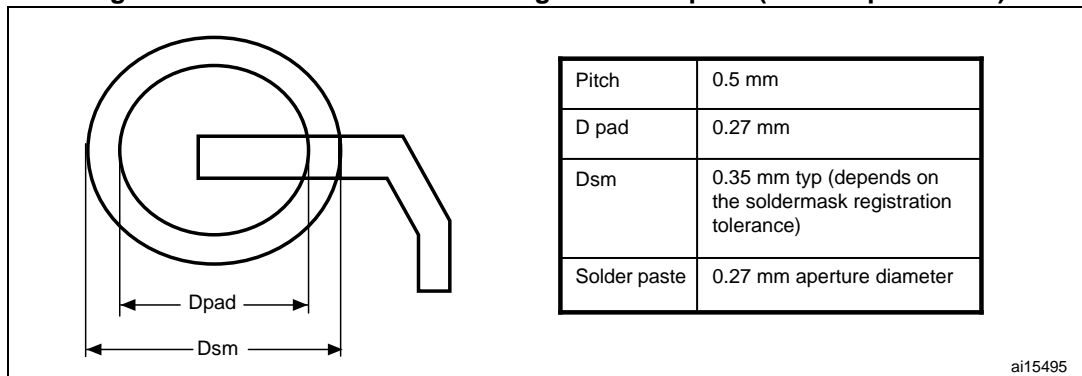
Symbol	millimeters			inches <sup>(1)</sup>		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.460	0.530	0.600	0.0181	0.0209	0.0236
A1	0.050	0.080	0.110	0.0020	0.0031	0.0043
A2	0.400	0.450	0.500	0.0157	0.0177	0.0197
A3	-	0.130	-	-	0.0051	-
A4	0.270	0.320	0.370	0.0106	0.0126	0.0146
b	0.200	0.250	0.300	0.0079	0.0098	0.0118
D	6.950	7.000	7.050	0.2736	0.2756	0.2776
D1	5.450	5.500	5.550	0.2146	0.2165	0.2185
E	6.950	7.000	7.050	0.2736	0.2756	0.2776
E1	5.450	5.500	5.550	0.2146	0.2165	0.2185
e	-	0.500	-	-	0.0197	-
F	0.700	0.750	0.800	0.0276	0.0295	0.0315

**Table 84. UFBGA100, 7 x 7 mm, 0.50 mm pitch, ultra fine pitch ball grid array package mechanical data (continued)**

Symbol	millimeters			inches <sup>(1)</sup>		
	Min.	Typ.	Max.	Min.	Typ.	Max.
ddd	-	-	0.100	-	-	0.0039
eee	-	-	0.150	-	-	0.0059
fff	-	-	0.050	-	-	0.0020

1. Values in inches are converted from mm and rounded to 4 decimal digits.

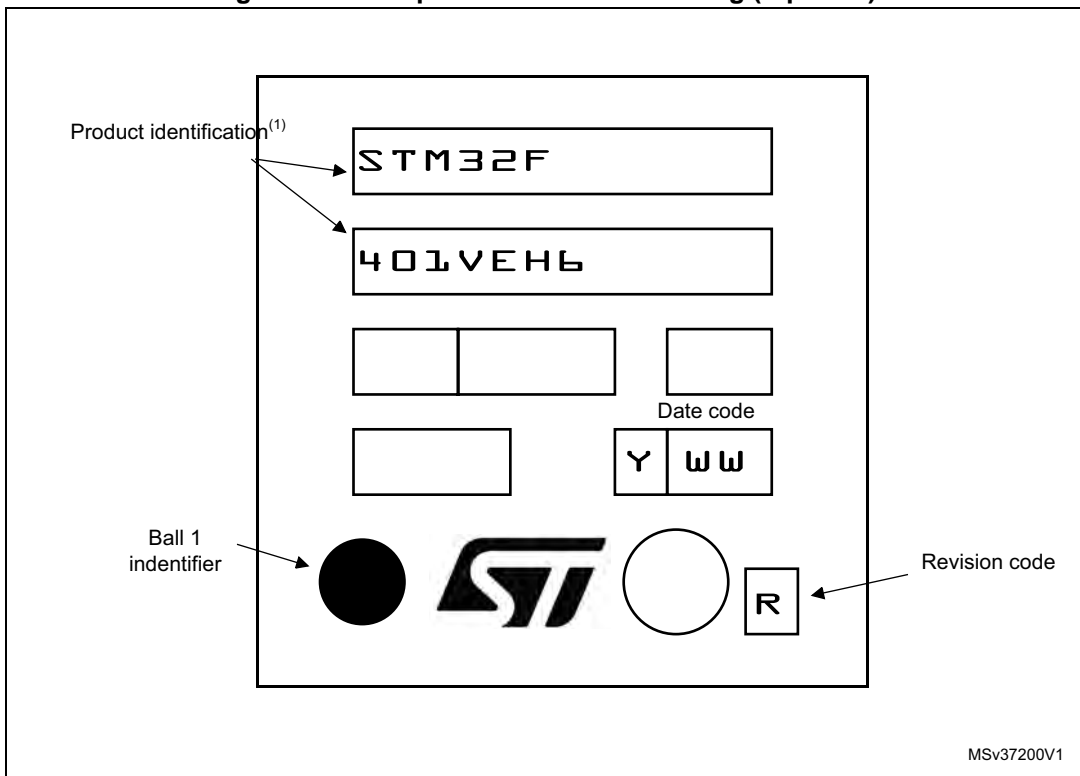
**Figure 59. Recommended PCB design rules for pads (0.5 mm-pitch BGA)**



1. Non solder mask defined (NSMD) pads are recommended.
2. 4 to 6 mils solder paste screen printing process.

Device marking

Figure 60. Example of UFBGA100 marking (top view)



1. Parts marked as "ES", "E" or accompanied by an Engineering Sample notification letter, are not yet qualified and therefore not yet ready to be used in production and any consequences deriving from such usage will not be at ST charge. In no event, ST will be liable for any customer usage of these engineering samples in production. ST Quality has to be contacted prior to any decision to use these Engineering samples to run qualification activity.



## 7.2 Thermal characteristics

The maximum chip junction temperature ( $T_{Jmax}$ ) must never exceed the values given in [Table 14: General operating conditions on page 60](#).

The maximum chip-junction temperature,  $T_J max.$ , in degrees Celsius, may be calculated using the following equation:

$$T_J max = T_A max + (PD max \times \Theta_{JA})$$

Where:

- $T_A max$  is the maximum ambient temperature in °C,
- $\Theta_{JA}$  is the package junction-to-ambient thermal resistance, in °C/W,
- PD max is the sum of  $P_{INT max}$  and  $P_{I/O max}$  ( $PD max = P_{INT max} + P_{I/O max}$ ),
- $P_{INT max}$  is the product of  $I_{DD}$  and  $V_{DD}$ , expressed in Watts. This is the maximum chip internal power.

$P_{I/O max}$  represents the maximum power dissipation on output pins where:

$$P_{I/O max} = \Sigma (V_{OL} \times I_{OL}) + \Sigma ((V_{DD} - V_{OH}) \times I_{OH}),$$

taking into account the actual  $V_{OL} / I_{OL}$  and  $V_{OH} / I_{OH}$  of the I/Os at low and high level in the application.

**Table 85. Package thermal characteristics**

Symbol	Parameter	Value	Unit
$\Theta_{JA}$	Thermal resistance junction-ambient UFQFPN48	32	°C/W
	Thermal resistance junction-ambient WLCSP49	51	
	Thermal resistance junction-ambient LQFP64	50	
	Thermal resistance junction-ambient LQFP100	42	
	Thermal resistance junction-ambient UFBGA100	56	

### 7.2.1 Reference document

JESD51-2 Integrated Circuits Thermal Test Method Environment Conditions - Natural Convection (Still Air). Available from [www.jedec.org](http://www.jedec.org).

# 8 Part numbering

**Table 86. Ordering information scheme**

Example:	STM32	F	401	C	E	Y	6	TR
<b>Device family</b> STM32 = ARM-based 32-bit microcontroller								
<b>Product type</b> F = General-purpose								
<b>Device subfamily</b> 401 = 401 family								
<b>Pin count</b> C = 48/49 pins R = 64 pins V = 100 pins								
<b>Flash memory size</b> D = 384 Kbytes of Flash memory E = 512 Kbytes of Flash memory								
<b>Package</b> H = UFBGA T = LQFP U = UFQFPN Y = WLCSP								
<b>Temperature range</b> 6 = Industrial temperature range, -40 to 85 °C								
<b>Packing</b> TR = tape and reel No character = tray or tube								

Table 87. Device order codes

Reference	Order codes
STM32F401xD	STM32F401CDY6, STM32F401RDT6, STM32F401VDT6, STM32F401CDU6, STM32F401VDH6
STM32F401xE	STM32F401CEY6, STM32F401RET6, STM32F401VET6, STM32F401CEU6, STM32F401VEH6

## 9 Revision history

**Table 88. Document revision history**

Date	Revision	Changes
16-Jan-2014	1	Initial release.
24-Feb-2014	2	Updated Flash memory size in <a href="#">Table 2: STM32F401xD/xE features and peripheral counts</a> . Added alternate functions mapped on PCx, PDx and PEx GPIOs in <a href="#">Table 9: Alternate function mapping</a>
22-Jan-2015	3	Updated UFQFPN48 in <a href="#">Table 3: Regulator ON/OFF and internal power supply supervisor availability</a> . Updated number of EXTI lines in <a href="#">Section 3.10: External interrupt/event controller (EXTI)</a> . Updated <a href="#">Table 54: I/O static characteristics</a> . Added WLCSP49 <a href="#">Figure 47: WLCSP49 0.4 mm pitch wafer level chip size recommended footprint</a> and <a href="#">Table 80: WLCSP49 recommended PCB design rules (0.4 mm pitch)</a> . Updated <a href="#">Figure 48: Example of WLCSP49 marking (top view)</a> . Updated <a href="#">Figure 51: Example of UFQFPN48 marking (top view)</a> . Updated <a href="#">Figure 54: Example of LQFP64 marking (top view)</a> . Updated <a href="#">Figure 57: Example of LQPF100 marking (top view)</a> . Updated <a href="#">Figure 60: Example of UFBGA100 marking (top view)</a> . Added notes below all engineering sample marking schematics.

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# RM0368

## Reference manual

### STM32F401xB/C and STM32F401xD/E advanced ARM<sup>®</sup>-based 32-bit MCUs

## Introduction

This Reference manual targets application developers. It provides complete information on how to use the memory and the peripherals of the STM32F401xB/C and STM32F401xD/E microcontrollers.

STM32F401xB/C and STM32F401xD/E are part of the STM32F401xx family of microcontrollers with different memory sizes, packages and peripherals.

For ordering information, mechanical and electrical device characteristics refer to the datasheets.

For information on the ARM<sup>®</sup> Cortex<sup>®</sup>-M4 with FPU core, refer to the *Cortex<sup>®</sup>-M4 with FPU Technical Reference Manual*.

## Related documents

Available from STMicroelectronics web site (<http://www.st.com>):

- STM32F401xB/C datasheet
- STM32F401xD/E datasheet
- For information on the ARM<sup>®</sup>-M4 core with FPU, refer to the *STM32F3xx/F4xxx Cortex<sup>®</sup>-M4 with FPU-M4 programming manual (PM0214)*.

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# 1 Documentation conventions

## 1.1 List of abbreviations for registers

The following abbreviations are used in register descriptions:

read/write (rw)	Software can read and write to these bits.
read-only (r)	Software can only read these bits.
write-only (w)	Software can only write to this bit. Reading the bit returns the reset value.
read/clear (rc_w1)	Software can read as well as clear this bit by writing 1. Writing '0' has no effect on the bit value.
read/clear (rc_w0)	Software can read as well as clear this bit by writing 0. Writing '1' has no effect on the bit value.
read/clear by read (rc_r)	Software can read this bit. Reading this bit automatically clears it to '0'. Writing '0' has no effect on the bit value.
read/set (rs)	Software can read as well as set this bit. Writing '0' has no effect on the bit value.
read-only write trigger (rt_w)	Software can read this bit. Writing '0' or '1' triggers an event but has no effect on the bit value.
toggle (t)	Software can only toggle this bit by writing '1'. Writing '0' has no effect.
Reserved (Res.)	Reserved bit, must be kept at reset value.

## 1.2 Glossary

This section gives a brief definition of acronyms and abbreviations used in this document:

- The CPU core integrates two debug ports:
  - JTAG debug port (JTAG-DP) provides a 5-pin standard interface based on the Joint Test Action Group (JTAG) protocol.
  - SWD debug port (SWD-DP) provides a 2-pin (clock and data) interface based on the Serial Wire Debug (SWD) protocol.  
For both the JTAG and SWD protocols, please refer to the Cortex<sup>®</sup>-M4 with FPU Technical Reference Manual
- Word: data/instruction of 32-bit length.
- Half word: data/instruction of 16-bit length.
- Byte: data of 8-bit length.
- Double word: data of 64-bit length.
- IAP (in-application programming): IAP is the ability to reprogram the Flash memory of a microcontroller while the user program is running.
- ICP (in-circuit programming): ICP is the ability to program the Flash memory of a microcontroller using the JTAG protocol, the SWD protocol or the bootloader while the device is mounted on the user application board.
- I-Code: this bus connects the Instruction bus of the CPU core to the Flash instruction interface. Prefetch is performed on this bus.
- D-Code: this bus connects the D-Code bus (literal load and debug access) of the CPU to the Flash data interface.
- Option bytes: product configuration bits stored in the Flash memory.
- OBL: option byte loader.
- AHB: advanced high-performance bus.
- CPU: refers to the Cortex<sup>®</sup>-M4 with FPU core.

## 1.3 Peripheral availability

For information on the availability and the number of instances of each peripheral in the various STM32F401xx salestypes, please refer to the STM32F401xB/C and STM32F401xD/E datasheets.



## 2 Memory and bus architecture

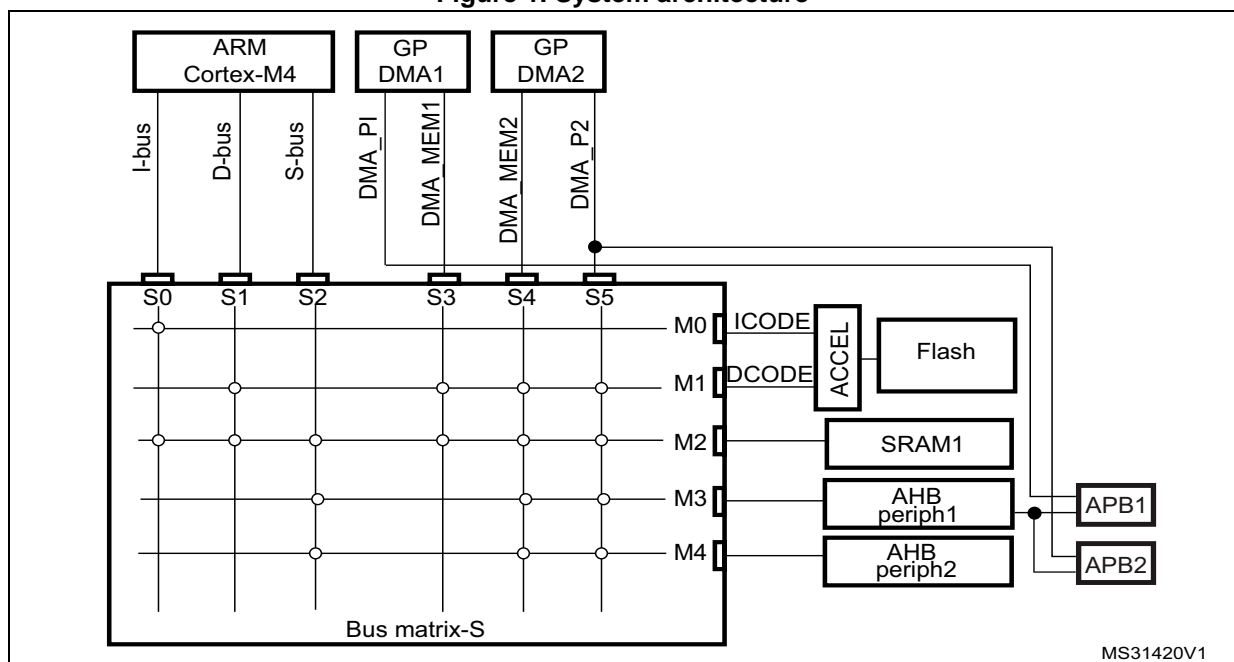
### 2.1 System architecture

In STM32F401xB/C and STM32F401xD/E, the main system consists of 32-bit multilayer AHB bus matrix that interconnects:

- Six masters:
  - Cortex<sup>®</sup>-M4 with FPU core I-bus, D-bus and S-bus
  - DMA1 memory bus
  - DMA2 memory bus
  - DMA2 peripheral bus
- Five slaves:
  - Internal Flash memory ICode bus
  - Internal Flash memory DCode bus
  - Main internal SRAM
  - AHB1 peripherals including AHB to APB bridges and APB peripherals
  - AHB2 peripherals

The bus matrix provides access from a master to a slave, enabling concurrent access and efficient operation even when several high-speed peripherals work simultaneously. This architecture is shown in [Figure 1](#).

**Figure 1. System architecture**



1. STM32F401xB/C: 128 KBytes / 256 KBytes Flash with 64 KBytes SRAM.  
 STM32F401xD/E: 384 KBytes / 512KBytes Flash with 96 KBytes SRAM.

### 2.1.1 I-bus

This bus connects the Instruction bus of the Cortex<sup>®</sup>-M4 with FPU core to the BusMatrix. This bus is used by the core to fetch instructions. The target of this bus is a memory containing code (internal Flash memory/SRAM).

### 2.1.2 D-bus

This bus connects the databus of the Cortex<sup>®</sup>-M4 with FPU to the BusMatrix. This bus is used by the core for literal load and debug access. The target of this bus is a memory containing code or data (internal Flash memory/SRAM).

### 2.1.3 S-bus

This bus connects the system bus of the Cortex<sup>®</sup>-M4 with FPU core to a BusMatrix. This bus is used to access data located in a peripheral or in SRAM. Instructions may also be fetched on this bus (less efficient than ICode). The targets of this bus are the internal SRAM, the AHB1 peripherals including the APB peripherals and the AHB2 peripherals.

### 2.1.4 DMA memory bus

This bus connects the DMA memory bus master interface to the BusMatrix. It is used by the DMA to perform transfer to/from memories. The targets of this bus are data memories: internal Flash memory, internal SRAM and additionally for S4 the AHB1/AHB2 peripherals including the APB peripherals.

### 2.1.5 DMA peripheral bus

This bus connects the DMA peripheral master bus interface to the BusMatrix. This bus is used by the DMA to access AHB peripherals or to perform memory-to-memory transfers. The targets of this bus are the AHB and APB peripherals plus data memories: Flash memory and internal SRAM.

### 2.1.6 BusMatrix

The BusMatrix manages the access arbitration between masters. The arbitration uses a round-robin algorithm.

### 2.1.7 AHB/APB bridges (APB)

The two AHB/APB bridges, APB1 and APB2, provide full synchronous connections between the AHB and the two APB buses, allowing flexible selection of the peripheral frequency.

Refer to the device datasheets for more details on APB1 and APB2 maximum frequencies, and to [Table 1](#) for the address mapping of AHB and APB peripherals.

After each device reset, all peripheral clocks are disabled (except for the SRAM and Flash memory interface). Before using a peripheral you have to enable its clock in the RCC\_AHBxENR or RCC\_APBxENR register.

*Note:* When a 16- or an 8-bit access is performed on an APB register, the access is transformed into a 32-bit access: the bridge duplicates the 16- or 8-bit data to feed the 32-bit vector.

## 2.2 Memory organization

Program memory, data memory, registers and I/O ports are organized within the same linear 4 Gbyte address space.

The bytes are coded in memory in little endian format. The lowest numbered byte in a word is considered the word's least significant byte and the highest numbered byte, the word's most significant.

For the detailed mapping of peripheral registers, please refer to the related chapters.

The addressable memory space is divided into 8 main blocks, each of 512 MB.

All the memory areas that are not allocated to on-chip memories and peripherals are considered "Reserved"). Refer to the memory map figure in the product datasheet.

## 2.3 Memory map

See the datasheet corresponding to your device for a comprehensive diagram of the memory map. [Table 1](#) gives the boundary addresses of the peripherals available in STM32F401xB/C and STM32F401xD/E devices.

**Table 1. STM32F401xB/C and STM32F401xD/E register boundary addresses**

Boundary address	Peripheral	Bus	Register map	
0x5000 0000 - 0x5003 FFFF	USB OTG FS	AHB2	<a href="#">Section 22.16.6: OTG_FS register map on page 746</a>	
0x4002 6400 - 0x4002 67FF	DMA2	AHB1	<a href="#">Section 9.5.11: DMA register map on page 197</a>	
0x4002 6000 - 0x4002 63FF	DMA1			
0x4002 3C00 - 0x4002 3FFF	Flash interface register			<a href="#">Section 3.8: Flash interface registers on page 60</a>
0x4002 3800 - 0x4002 3BFF	RCC			<a href="#">Section 6.3.22: RCC register map on page 136</a>
0x4002 3000 - 0x4002 33FF	CRC			<a href="#">Section 4.4.4: CRC register map on page 70</a>
0x4002 1C00 - 0x4002 1FFF	GPIOH			<a href="#">Section 8.4.11: GPIO register map on page 162</a>
0x4002 1000 - 0x4002 13FF	GPIOE			
0x4002 0C00 - 0x4002 0FFF	GIPOD			
0x4002 0800 - 0x4002 0BFF	GPIOC			
0x4002 0400 - 0x4002 07FF	GPIOB			
0x4002 0000 - 0x4002 03FF	GPIOA			

**Table 1. STM32F401xB/C and STM32F401xD/E register boundary addresses (continued)**

Boundary address	Peripheral	Bus	Register map
0x4001 4800 - 0x4001 4BFF	TIM11	APB2	<a href="#">Section 14.5.12: TIM10/11 register map on page 413</a>
0x4001 4400 - 0x4001 47FF	TIM10		
0x4001 4000 - 0x4001 43FF	TIM9		
0x4001 3C00 - 0x4001 3FFF	EXTI		
0x4001 3800 - 0x4001 3BFF	SYSCFG		
0x4001 3400 - 0x4001 37FF	SPI4		
0x4001 3000 - 0x4001 33FF	SPI1		
0x4001 2C00 - 0x4001 2FFF	SDIO		
0x4001 2000 - 0x4001 23FF	ADC1		
0x4001 1400 - 0x4001 17FF	USART6		
0x4001 1000 - 0x4001 13FF	USART1		
0x4001 0000 - 0x4001 03FF	TIM1		
0x4000 7000 - 0x4000 73FF	PWR		
0x4000 5C00 - 0x4000 5FFF	I2C3	<a href="#">Section 18.6.11: I2C register map on page 500</a>	
0x4000 5800 - 0x4000 5BFF	I2C2		
0x4000 5400 - 0x4000 57FF	I2C1		
0x4000 4400 - 0x4000 47FF	USART2	<a href="#">Section 19.6.8: USART register map on page 552</a>	
0x4000 4000 - 0x4000 43FF	I2S3ext	<a href="#">Section 20.5.10: SPI register map on page 606</a>	
0x4000 3C00 - 0x4000 3FFF	SPI3 / I2S3		
0x4000 3800 - 0x4000 3BFF	SPI2 / I2S2		
0x4000 3400 - 0x4000 37FF	I2S2ext		
0x4000 3000 - 0x4000 33FF	IWDG	<a href="#">Section 15.4.5: IWDG register map on page 419</a>	
0x4000 2C00 - 0x4000 2FFF	WWDG	<a href="#">Section 16.6.4: WWDG register map on page 426</a>	
0x4000 2800 - 0x4000 2BFF	RTC & BKP Registers	<a href="#">Section 17.6.21: RTC register map on page 464</a>	
0x4000 0C00 - 0x4000 0FFF	TIM5	<a href="#">Section 13.4.21: TIMx register map on page 368</a>	
0x4000 0800 - 0x4000 0BFF	TIM4		
0x4000 0400 - 0x4000 07FF	TIM3		
0x4000 0000 - 0x4000 03FF	TIM2		

### 2.3.1 Embedded SRAM

STM32F401xB/C devices feature 64 Kbytes and STM32F401xD/E devices feature 96 Kbytes of system SRAM.

The embedded SRAM can be accessed as bytes, half-words (16 bits) or full words (32 bits). Read and write operations are performed at CPU speed with 0 wait state.

The CPU can access the embedded SRAM through the System Bus or through the I-Code/D-Code buses when boot from SRAM is selected or when physical remap is selected ([Section 7.2.1: SYSCFG memory remap register \(SYSCFG\\_MEMRMP\)](#) in the SYSCFG controller). To get the max performance on SRAM execution, physical remap should be selected (boot or software selection).

### 2.3.2 Flash memory overview

The Flash memory interface manages CPU AHB I-Code and D-Code accesses to the Flash memory. It implements the erase and program Flash memory operations and the read and write protection mechanisms. It accelerates code execution with a system of instruction prefetch and cache lines.

The Flash memory is organized as follows:

- A main memory block divided into sectors.
- System memory from which the device boots in System memory boot mode
- 512 OTP (one-time programmable) bytes for user data.
- Option bytes to configure read and write protection, BOR level, watchdog software/hardware and reset when the device is in Standby or Stop mode.

Refer to [Section 3: Embedded Flash memory interface](#) for more details.

### 2.3.3 Bit banding

The Cortex<sup>®</sup>-M4 with FPU memory map includes two bit-band regions. These regions map each word in an alias region of memory to a bit in a bit-band region of memory. Writing to a word in the alias region has the same effect as a read-modify-write operation on the targeted bit in the bit-band region.

In the STM32F4xx devices both the peripheral registers and the SRAM are mapped to a bit-band region, so that single bit-band write and read operations are allowed. The operations are only available for Cortex<sup>®</sup>-M4 with FPU accesses, and not from other bus masters (e.g. DMA).

A mapping formula shows how to reference each word in the alias region to a corresponding bit in the bit-band region. The mapping formula is:

$$bit\_word\_addr = bit\_band\_base + (byte\_offset \times 32) + (bit\_number \times 4)$$

where:

- *bit\_word\_addr* is the address of the word in the alias memory region that maps to the targeted bit
- *bit\_band\_base* is the starting address of the alias region
- *byte\_offset* is the number of the byte in the bit-band region that contains the targeted bit
- *bit\_number* is the bit position (0-7) of the targeted bit

### Example

The following example shows how to map bit 2 of the byte located at SRAM address 0x20000300 to the alias region:

$$0x22006008 = 0x22000000 + (0x300*32) + (2*4)$$

Writing to address 0x22006008 has the same effect as a read-modify-write operation on bit 2 of the byte at SRAM address 0x20000300.

Reading address 0x22006008 returns the value (0x01 or 0x00) of bit 2 of the byte at SRAM address 0x20000300 (0x01: bit set; 0x00: bit reset).

For more information on bit-banding, please refer to the *Cortex<sup>®</sup>-M4 with FPU programming manual* (see [Related documents on page 1](#)).

## 2.4 Boot configuration

Due to its fixed memory map, the code area starts from address 0x0000 0000 (accessed through the ICode/DCode buses) while the data area (SRAM) starts from address 0x2000 0000 (accessed through the system bus). The Cortex<sup>®</sup>-M4 with FPU CPU always fetches the reset vector on the ICode bus, which implies to have the boot space available only in the code area (typically, Flash memory). STM32F4xx microcontrollers implement a special mechanism to be able to boot from other memories (like the internal SRAM).

In the STM32F4xx, three different boot modes can be selected through the BOOT[1:0] pins as shown in [Table 2](#).

**Table 2. Boot modes**

Boot mode selection pins		Boot mode	Aliasing
BOOT1	BOOT0		
x	0	Main Flash memory	Main Flash memory is selected as the boot space
0	1	System memory	System memory is selected as the boot space
1	1	Embedded SRAM	Embedded SRAM is selected as the boot space

The values on the BOOT pins are latched on the 4th rising edge of SYSCLK after a reset. It is up to the user to set the BOOT1 and BOOT0 pins after reset to select the required boot mode.

BOOT0 is a dedicated pin while BOOT1 is shared with a GPIO pin. Once BOOT1 has been sampled, the corresponding GPIO pin is free and can be used for other purposes.

The BOOT pins are also resampled when the device exits the Standby mode. Consequently, they must be kept in the required Boot mode configuration when the device is in the Standby mode. After this startup delay is over, the CPU fetches the top-of-stack value from address 0x0000 0000, then starts code execution from the boot memory starting from 0x0000 0004.

*Note:* *When the device boots from SRAM, in the application initialization code, you have to relocate the vector table in SRAM using the NVIC exception table and the offset register.*

### Embedded bootloader

The embedded bootloader mode is used to reprogram the Flash memory using one of the following serial interfaces:

- USART1 (PA9/PA10)
- USART2 (PD5/PD6)
- I2C1 (PB6/PB7)
- I2C2 (PB10/PB3)
- I2C3 (PA8/PB4)
- SPI1 (PA4/PA5/PA6/PA7)
- SPI2 (PB12/PB13/PB14/PB15)
- SPI3 (PA15/PC10/PC11/PC12)
- USB OTG FS (PA11/12) in Device mode (DFU: device firmware upgrade).

The USART peripherals operate at the internal 16 MHz oscillator (HSI) frequency, while the USB OTG FS require an external clock (HSE) multiple of 1 MHz (ranging from 4 to 26 MHz).

The embedded bootloader code is located in system memory. It is programmed by ST during production. For additional information, refer to application note AN2606.

### Physical remap in STM32F401xB/C and STM32F401xD/E

Once the boot pins are selected, the application software can modify the memory accessible in the code area (in this way the code can be executed through the ICode bus in place of the System bus). This modification is performed by programming the [Section 7.2.1: SYSCFG memory remap register \(SYSCFG\\_MEMRMP\)](#) in the SYSCFG controller.

The following memories can thus be remapped:

- Main Flash memory
- System memory
- Embedded SRAM1

**Table 3. Memory mapping vs. Boot mode/physical remap in STM32F401xB/C**

Addresses	Boot/Remap in main Flash memory	Boot/Remap in embedded SRAM	Boot/Remap in System memory
0x2000 0000 - 0x2000 FFFF	SRAM1 (64 KB)	SRAM1 (64 KB)	SRAM1 (64 KB)
0x1FFF 0000 - 0x1FFF 77FF	System memory	System memory	System memory
0x0804 0000 - 0x1FFE FFFF	Reserved	Reserved	Reserved
0x0800 0000 - 0x0803 FFFF	Flash memory	Flash memory	Flash memory
0x0400 000 - 0x07FF FFFF	Reserved	Reserved	Reserved
0x0000 0000 - 0x0003 FFFF <sup>(1)</sup>	Flash (256 KB) Aliased	SRAM1 (64 KB) Aliased	System memory (30 KB) Aliased

1. Even when aliased in the boot memory space, the related memory is still accessible at its original memory space.

**Table 4. Memory mapping vs. Boot mode/physical remap in STM32F401xD/E**

Addresses	Boot/Remap in main Flash memory	Boot/Remap in embedded SRAM	Boot/Remap in System memory
0x2000 0000 - 0x2001 7FFF	SRAM1 (96 KB)	SRAM1 (96KB)	SRAM1 (96KB)
0x1FFF 0000 - 0x1FFF 77FF	System memory	System memory	System memory
0x0804 0000 - 0x1FFE FFFF	Reserved	Reserved	Reserved
0x0800 0000 - 0x0807 FFFF	Flash memory	Flash memory	Flash memory
0x0400 000 - 0x07FF FFFF	Reserved	Reserved	Reserved
0x0000 0000 - 0x0007 FFFF <sup>(1)</sup>	Flash (512 KB) Aliased	SRAM1 (96 KB) Aliased	System memory (30 KB) Aliased

1. Even when aliased in the boot memory space, the related memory is still accessible at its original memory space.



### 3 Embedded Flash memory interface

#### 3.1 Introduction

The Flash memory interface manages CPU AHB I-Code and D-Code accesses to the Flash memory. It implements the erase and program Flash memory operations and the read and write protection mechanisms.

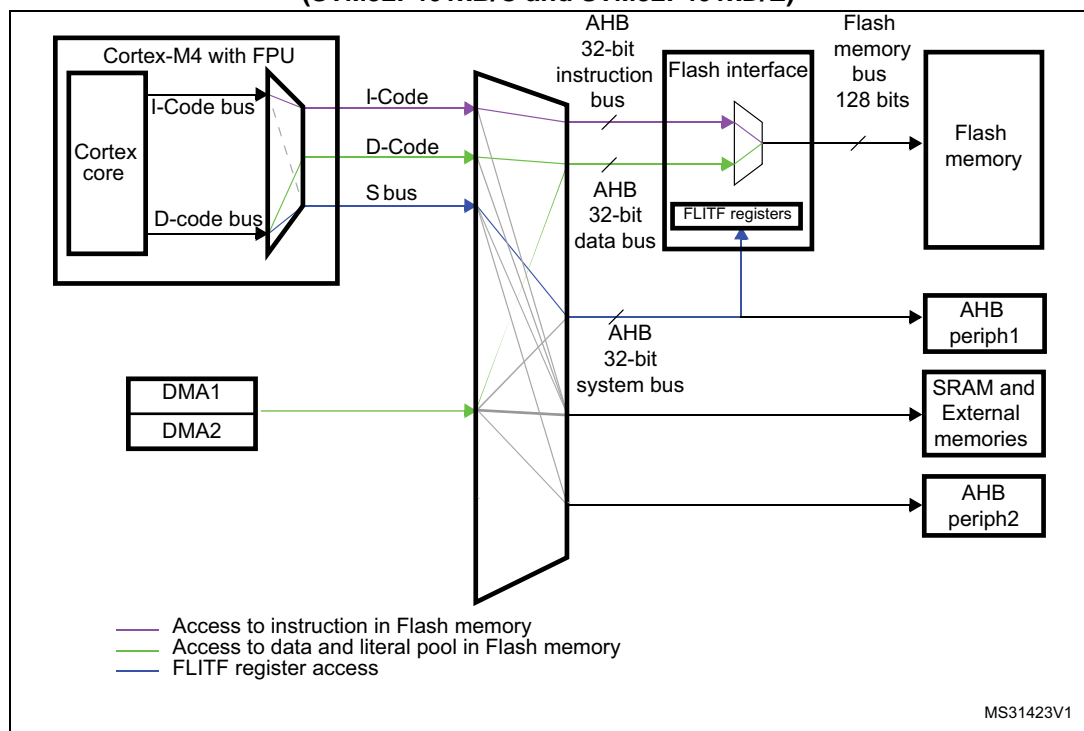
The Flash memory interface accelerates code execution with a system of instruction prefetch and cache lines.

#### 3.2 Main features

- Flash memory read operations
- Flash memory program/erase operations
- Read / write protections
- Prefetch on I-Code
- 64 cache lines of 128 bits on I-Code
- 8 cache lines of 128 bits on D-Code

Figure 2 shows the Flash memory interface connection inside the system architecture.

**Figure 2. Flash memory interface connection inside system architecture (STM32F401xB/C and STM32F401xD/E)**



MS31423V1

### 3.3 Embedded Flash memory in STM32F401xB/C and STM32F401xD/E

The Flash memory has the following main features:

- Capacity up to 256 Kbytes for STM32F401xB/C and up to 512 Kbytes for STM32F401xD/E
- 128 bits wide data read
- Byte, half-word, word and double word write
- Sector and mass erase
- Memory organization

The Flash memory is organized as follows:

- A main memory block divided into 4 sectors of 16 Kbytes, 1 sector of 64 Kbytes, 1 sector of 128 Kbytes (STM32F401xB/C) or 3 sectors of 128 Kbytes (STM32F401xD/E)
- System memory from which the device boots in System memory boot mode
- 512 OTP (one-time programmable) bytes for user data  
The OTP area contains 16 additional bytes used to lock the corresponding OTP data block.
- Option bytes to configure read and write protection, BOR level, watchdog software/hardware and reset when the device is in Standby or Stop mode.
- Low-power modes (for details refer to the Power control (PWR) section of the reference manual)

**Table 5. Flash module organization (STM32F401xB/C and STM32F401xD/E)**

Block	Name	Block base addresses	Size
Main memory	Sector 0	0x0800 0000 - 0x0800 3FFF	16 Kbytes
	Sector 1	0x0800 4000 - 0x0800 7FFF	16 Kbytes
	Sector 2	0x0800 8000 - 0x0800 BFFF	16 Kbytes
	Sector 3	0x0800 C000 - 0x0800 FFFF	16 Kbytes
	Sector 4	0x0801 0000 - 0x0801 FFFF	64 Kbytes
	Sector 5	0x0802 0000 - 0x0803 FFFF	128 Kbytes
	Sector 6	0x0804 0000 - 0x0805 FFFF	128 Kbytes
	Sector 7	0x0806 0000 - 0x0807 FFFF	128 Kbytes
System memory		0x1FFF 0000 - 0x1FFF 77FF	30 Kbytes
OTP area		0x1FFF 7800 - 0x1FFF 7A0F	528 bytes
Option bytes		0x1FFF C000 - 0x1FFF C00F	16 bytes

### 3.4 Read interface

#### 3.4.1 Relation between CPU clock frequency and Flash memory read time

To correctly read data from Flash memory, the number of wait states (LATENCY) must be correctly programmed in the Flash access control register (FLASH\_ACR) according to the frequency of the CPU clock (HCLK) and the supply voltage of the device.

The prefetch buffer must be disabled when the supply voltage is below 2.1 V. The correspondence between wait states and CPU clock frequency is given in [Table 6](#).

- when  $VOS[1:0] = 0x01$ , the maximum value of  $f_{HCLK} = 60$  MHz.

- when  $VOS[1:0] = 0x10$ , the maximum value of  $f_{HCLK} = 84$  MHz.

**Table 6. Number of wait states according to CPU clock (HCLK) frequency**

Wait states (WS) (LATENCY)	HCLK (MHz)			
	Voltage range 2.7 V - 3.6 V	Voltage range 2.4 V - 2.7 V	Voltage range 2.1 V - 2.4 V	Voltage range 1.71 V - 2.1 V
0 WS (1 CPU cycle)	$0 < HCLK \leq 30$	$0 < HCLK \leq 24$	$0 < HCLK \leq 18$	$0 < HCLK \leq 16$
1 WS (2 CPU cycles)	$30 < HCLK \leq 60$	$24 < HCLK \leq 48$	$18 < HCLK \leq 36$	$16 < HCLK \leq 32$
2 WS (3 CPU cycles)	$60 < HCLK \leq 84$	$48 < HCLK \leq 72$	$36 < HCLK \leq 54$	$32 < HCLK \leq 48$
3 WS (4 CPU cycles)		$72 < HCLK \leq 84$	$54 < HCLK \leq 72$	$48 < HCLK \leq 64$
4 WS (5 CPU cycles)	-	-	$72 < HCLK \leq 84$	$64 < HCLK \leq 80$
5 WS (6 CPU cycles)	-	-	-	$80 < HCLK \leq 84$

After reset, the CPU clock frequency is 16 MHz and 0 wait state (WS) is configured in the FLASH\_ACR register.

It is highly recommended to use the following software sequences to tune the number of wait states needed to access the Flash memory with the CPU frequency.

#### Increasing the CPU frequency

1. Program the new number of wait states to the LATENCY bits in the FLASH\_ACR register
2. Check that the new number of wait states is taken into account to access the Flash memory by reading the FLASH\_ACR register
3. Modify the CPU clock source by writing the SW bits in the RCC\_CFGR register
4. If needed, modify the CPU clock prescaler by writing the HPRE bits in RCC\_CFGR
5. Check that the new CPU clock source or/and the new CPU clock prescaler value is/are taken into account by reading the clock source status (SWS bits) or/and the AHB prescaler value (HPRE bits), respectively, in the RCC\_CFGR register.

### Decreasing the CPU frequency

1. Modify the CPU clock source by writing the SW bits in the RCC\_CFGR register
2. If needed, modify the CPU clock prescaler by writing the HPRE bits in RCC\_CFGR
3. Check that the new CPU clock source or/and the new CPU clock prescaler value is/are taken into account by reading the clock source status (SWS bits) or/and the AHB prescaler value (HPRE bits), respectively, in the RCC\_CFGR register
4. Program the new number of wait states to the LATENCY bits in FLASH\_ACR
5. Check that the new number of wait states is used to access the Flash memory by reading the FLASH\_ACR register

*Note:* A change in CPU clock configuration or wait state (WS) configuration may not be effective straight away. To make sure that the current CPU clock frequency is the one you have configured, you can check the AHB prescaler factor and clock source status values. To make sure that the number of WS you have programmed is effective, you can read the FLASH\_ACR register.

### 3.4.2 Adaptive real-time memory accelerator (ART Accelerator™)

The proprietary Adaptive real-time (ART) memory accelerator is optimized for STM32 industry-standard ARM® Cortex®-M4 with FPU processors. It balances the inherent performance advantage of the ARM® Cortex®-M4 with FPU over Flash memory technologies, which normally requires the processor to wait for the Flash memory at higher operating frequencies.

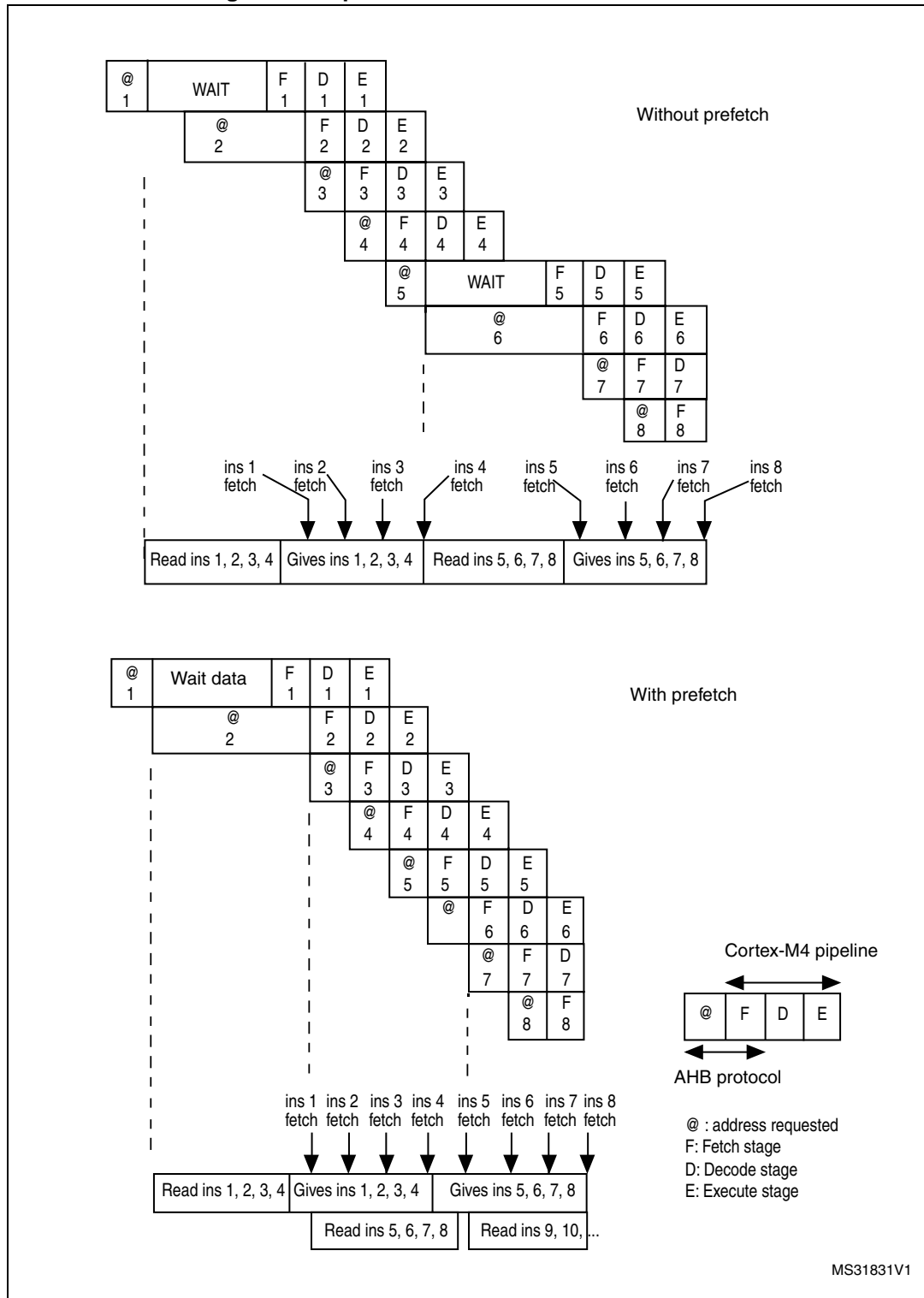
To release the processor full performance, the accelerator implements an instruction prefetch queue and branch cache which increases program execution speed from the 128-bit Flash memory. Based on CoreMark benchmark, the performance achieved thanks to the ART accelerator is equivalent to 0 wait state program execution from Flash memory at a CPU frequency up to 84 MHz.

#### Instruction prefetch

Each Flash memory read operation provides 128 bits from either four instructions of 32 bits or 8 instructions of 16 bits according to the program launched. So, in case of sequential code, at least four CPU cycles are needed to execute the previous read instruction line. Prefetch on the I-Code bus can be used to read the next sequential instruction line from the Flash memory while the current instruction line is being requested by the CPU. Prefetch is enabled by setting the PRFTEN bit in the FLASH\_ACR register. This feature is useful if at least one wait state is needed to access the Flash memory.

*Figure 3* shows the execution of sequential 32-bit instructions with and without prefetch when 3 WSs are needed to access the Flash memory.

Figure 3. Sequential 32-bit instruction execution



When the code is not sequential (branch), the instruction may not be present in the currently used instruction line or in the prefetched instruction line. In this case (miss), the penalty in terms of number of cycles is at least equal to the number of wait states.

### Instruction cache memory

To limit the time lost due to jumps, it is possible to retain 64 lines of 128 bits in an instruction cache memory. This feature can be enabled by setting the instruction cache enable (ICEN) bit in the FLASH\_ACR register. Each time a miss occurs (requested data not present in the currently used instruction line, in the prefetched instruction line or in the instruction cache memory), the line read is copied into the instruction cache memory. If some data contained in the instruction cache memory are requested by the CPU, they are provided without inserting any delay. Once all the instruction cache memory lines have been filled, the LRU (least recently used) policy is used to determine the line to replace in the instruction memory cache. This feature is particularly useful in case of code containing loops.

### Data management

Literal pools are fetched from Flash memory through the D-Code bus during the execution stage of the CPU pipeline. The CPU pipeline is consequently stalled until the requested literal pool is provided. To limit the time lost due to literal pools, accesses through the AHB databus D-Code have priority over accesses through the AHB instruction bus I-Code.

If some literal pools are frequently used, the data cache memory can be enabled by setting the data cache enable (DCEN) bit in the FLASH\_ACR register. This feature works like the instruction cache memory, but the retained data size is limited to 8 rows of 128 bits.

*Note:* Data in user configuration sector are not cacheable.

## 3.5 Erase and program operations

For any Flash memory program operation (erase or program), the CPU clock frequency (HCLK) must be at least 1 MHz. The contents of the Flash memory are not guaranteed if a device reset occurs during a Flash memory operation.

Any attempt to read the Flash memory on STM32F4xx while it is being written or erased, causes the bus to stall. Read operations are processed correctly once the program operation has completed. This means that code or data fetches cannot be performed while a write/erase operation is ongoing.

### 3.5.1 Unlocking the Flash control register

After reset, write is not allowed in the Flash control register (FLASH\_CR) to protect the Flash memory against possible unwanted operations due, for example, to electric disturbances. The following sequence is used to unlock this register:

1. Write KEY1 = 0x45670123 in the Flash key register (FLASH\_KEYR)
2. Write KEY2 = 0xCDEF89AB in the Flash key register (FLASH\_KEYR)

Any wrong sequence will return a bus error and lock up the FLASH\_CR register until the next reset.

The FLASH\_CR register can be locked again by software by setting the LOCK bit in the FLASH\_CR register.

*Note:* The FLASH\_CR register is not accessible in write mode when the BSY bit in the FLASH\_SR register is set. Any attempt to write to it with the BSY bit set will cause the AHB bus to stall until the BSY bit is cleared.

### 3.5.2 Program/erase parallelism

The Parallelism size is configured through the PSIZE field in the FLASH\_CR register. It represents the number of bytes to be programmed each time a write operation occurs to the Flash memory. PSIZE is limited by the supply voltage and by whether the external V<sub>PP</sub> supply is used or not. It must therefore be correctly configured in the FLASH\_CR register before any programming/erasing operation.

A Flash memory erase operation can only be performed by sector, or for the whole Flash memory (mass erase). The erase time depends on PSIZE programmed value. For more details on the erase time, refer to the electrical characteristics section of the device datasheet.

Table 7 provides the correct PSIZE values.

**Table 7. Program/erase parallelism**

	Voltage range 2.7 - 3.6 V with External V <sub>PP</sub>	Voltage range 2.7 - 3.6 V	Voltage range 2.4 - 2.7 V	Voltage range 2.1 - 2.4 V	Voltage range 1.7 V - 2.1 V
Parallelism size	x64	x32	x16		x8
PSIZE(1:0)	11	10	01		00

*Note:* Any program or erase operation started with inconsistent program parallelism/voltage range settings may lead to unpredicted results. Even if a subsequent read operation indicates that the logical value was effectively written to the memory, this value may not be retained.

To use V<sub>PP</sub>, an external high-voltage supply (between 8 and 9 V) must be applied to the V<sub>PP</sub> pad. The external supply must be able to sustain this voltage range even if the DC consumption exceeds 10 mA. It is advised to limit the use of V<sub>PP</sub> to initial programming on the factory line. The V<sub>PP</sub> supply must not be applied for more than an hour, otherwise the Flash memory might be damaged.

### 3.5.3 Erase

The Flash memory erase operation can be performed at sector level or on the whole Flash memory (Mass Erase). Mass Erase does not affect the OTP sector or the configuration sector.

#### Sector Erase

To erase a sector, follow the procedure below:

1. Check that no Flash memory operation is ongoing by checking the BSY bit in the FLASH\_SR register
2. Set the SER bit and select the sector out of the 5 sectors (for STM32F401xB/C) and out of 7 (for STM32F401xD/E) in the main memory block you wish to erase (SNB) in the FLASH\_CR register
3. Set the STRT bit in the FLASH\_CR register
4. Wait for the BSY bit to be cleared

### Mass Erase

To perform Mass Erase, the following sequence is recommended:

1. Check that no Flash memory operation is ongoing by checking the BSY bit in the FLASH\_SR register
2. Set the MER bit in the FLASH\_CR register
3. Set the STRT bit in the FLASH\_CR register
4. Wait for the BSY bit to be cleared

*Note:* If MERx and SER bits are both set in the FLASH\_CR register, mass erase is performed. If both MERx and SER bits are reset and the STRT bit is set, an unpredictable behavior may occur without generating any error flag. This condition should be forbidden.

### 3.5.4 Programming

#### Standard programming

The Flash memory programming sequence is as follows:

1. Check that no main Flash memory operation is ongoing by checking the BSY bit in the FLASH\_SR register.
2. Set the PG bit in the FLASH\_CR register
3. Perform the data write operation(s) to the desired memory address (inside main memory block or OTP area):
  - Byte access in case of x8 parallelism
  - Half-word access in case of x16 parallelism
  - Word access in case of x32 parallelism
  - Double word access in case of x64 parallelism
4. Wait for the BSY bit to be cleared.

*Note:* Successive write operations are possible without the need of an erase operation when changing bits from '1' to '0'. Writing '1' requires a Flash memory erase operation. If an erase and a program operation are requested simultaneously, the erase operation is performed first.

#### Programming errors

It is not allowed to program data to the Flash memory that would cross the 128-bit row boundary. In such a case, the write operation is not performed and a program alignment error flag (PGAERR) is set in the FLASH\_SR register.

The write access type (byte, half-word, word or double word) must correspond to the type of parallelism chosen (x8, x16, x32 or x64). If not, the write operation is not performed and a program parallelism error flag (PGPERR) is set in the FLASH\_SR register.

If the standard programming sequence is not respected (for example, if there is an attempt to write to a Flash memory address when the PG bit is not set), the operation is aborted and a program sequence error flag (PGSERR) is set in the FLASH\_SR register.



### Programming and caches

If a Flash memory write access concerns some data in the data cache, the Flash write access modifies the data in the Flash memory and the data in the cache.

If an erase operation in Flash memory also concerns data in the data or instruction cache, you have to make sure that these data are rewritten before they are accessed during code execution. If this cannot be done safely, it is recommended to flush the caches by setting the DCRST and ICRST bits in the FLASH\_CR register.

*Note:* The I/D cache should be flushed only when it is disabled (I/DCEN = 0).

### 3.5.5 Interrupts

Setting the end of operation interrupt enable bit (EOPIE) in the FLASH\_CR register enables interrupt generation when an erase or program operation ends, that is when the busy bit (BSY) in the FLASH\_SR register is cleared (operation completed, correctly or not). In this case, the end of operation (EOP) bit in the FLASH\_SR register is set.

If an error occurs during a program, an erase, or a read operation request, one of the following error flags is set in the FLASH\_SR register:

- PGAERR, PGPERR, PGSERR (Program error flags)
- WRPERR (Protection error flag)

In this case, if the error interrupt enable bit (ERRIE) is set in the FLASH\_SR register, an interrupt is generated and the operation error bit (OPERR) is set in the FLASH\_SR register.

*Note:* If several successive errors are detected (for example, in case of DMA transfer to the Flash memory), the error flags cannot be cleared until the end of the successive write requests.

**Table 8. Flash interrupt request**

Interrupt event	Event flag	Enable control bit
End of operation	EOP	EOPIE
Write protection error	WRPERR	ERRIE
Programming error	PGAERR, PGPERR, PGSERR	ERRIE

## 3.6 Option bytes

### 3.6.1 Description of user option bytes

The option bytes are configured by the end user depending on the application requirements. [Table 9](#) shows the organization of these bytes inside the user configuration sector.

**Table 9. Option byte organization**

Address	[63:16]	[15:0]
0x1FFF C000	Reserved	ROP & user option bytes (RDP & USER)
0x1FFF C008	Reserved	Write protection nWRP bits for 5 (STM32F401xB/C) and for sectors 0 to 7 (STM32F401xD/E)

**Table 10. Description of the option bytes**

<b>Option bytes (word, address 0x1FFF C000)</b>	
<p><b>RDP:</b> <i>Read protection option byte.</i>                      The read protection is used to protect the software code stored in Flash memory.</p>	
Bit 15:8	<p>0xAA: Level 0, no protection                      0xCC: Level 2, chip protection (debug and boot from RAM features disabled)                      Others: Level 1, read protection of memories (debug features limited)</p>
<p><b>USER:</b> User option byte                      This byte is used to configure the following features:                      Select the watchdog event: Hardware or software                      Reset event when entering the Stop mode                      Reset event when entering the Standby mode</p>	
Bit 7	<p><b>nRST_STDBY</b>                      0: Reset generated when entering the Standby mode                      1: No reset generated</p>
Bit 6	<p><b>nRST_STOP</b>                      0: Reset generated when entering the Stop mode                      1: No reset generated</p>
Bit 5	<p><b>WDG_SW</b>                      0: Hardware watchdog                      1: Software watchdog</p>
Bit 4	<p>0x0: Not used. For STM32F401xB/C do not change the default value of this bit which is "0" out of fab.</p>
Bits 3:2	<p><b>BOR_LEV:</b> BOR reset Level                      These bits contain the supply level threshold that activates/releases the reset. They can be written to program a new BOR level value into Flash memory.                      00: BOR Level 3 (VBOR3), brownout threshold level 3                      01: BOR Level 2 (VBOR2), brownout threshold level 2                      10: BOR Level 1 (VBOR1), brownout threshold level 1                      11: BOR off, POR/PDR reset threshold level is applied                      For full details on BOR characteristics, refer to the Electrical characteristics section of the product datasheet.</p>
Bits 1:0	<p>0x1: Not used</p>
<b>Option bytes (word, address 0x1FFF C008)</b>	
Bit 15	<p><b>SPRMOD:</b> Selection of Protection Mode of nWPRi bits                      0: nWPRi bits used for sector i write protection (Default)                      1: nWPRi bits used for sector i PCROP protection (Sector)</p>
Bits 14:6	<p>Reserved</p>

**Table 10. Description of the option bytes (continued)**

<b>nWRP:</b> <i>Flash memory write protection option bytes</i> Sectors 0 to 5 (STM32F401xB/C) and Sectors 0 to 7 (STM32F401xD/E) can be write protected.	
Bits 5:0	<b>nWRPi</b> If SPRMOD is reset (default value) : 0: Write protection active on sector i. 1: Write protection not active on sector i. If SPRMOD is set (active): 0: PCROP protection not active on sector i. 1: PCROP protection active on sector i.

### 3.6.2 Programming user option bytes

To run any operation on this sector, the option lock bit (OPTLOCK) in the Flash option control register (FLASH\_OPTCR) must be cleared. To be allowed to clear this bit, you have to perform the following sequence:

1. Write OPTKEY1 = 0x0819 2A3B in the Flash option key register (FLASH\_OPTKEYR)
2. Write OPTKEY2 = 0x4C5D 6E7F in the Flash option key register (FLASH\_OPTKEYR)

The user option bytes can be protected against unwanted erase/program operations by setting the OPTLOCK bit by software.

#### Modifying user option bytes

To modify the user option value, follow the sequence below:

1. Check that no Flash memory operation is ongoing by checking the BSY bit in the FLASH\_SR register
2. Write the desired option value in the FLASH\_OPTCR register.
3. Set the option start bit (OPTSTRT) in the FLASH\_OPTCR register
4. Wait for the BSY bit to be cleared.

*Note:* The value of an option is automatically modified by first erasing the user configuration sector and then programming all the option bytes with the values contained in the FLASH\_OPTCR register.

### 3.6.3 Read protection (RDP)

The user area in the Flash memory can be protected against read operations by an entrusted code. Three read protection levels are defined:

- Level 0: no read protection  
When the read protection level is set to Level 0 by writing 0xAA into the read protection option byte (RDP), all read/write operations (if no write protection is set) from/to the

Flash memory are possible in all boot configurations (Flash user boot, debug or boot from RAM).

- Level 1: read protection enabled

It is the default read protection level after option byte erase. The read protection Level 1 is activated by writing any value (except for 0xAA and 0xCC used to set Level 0 and Level 2, respectively) into the RDP option byte. When the read protection Level 1 is set:

- No access (read, erase, program) to Flash memory can be performed while the debug feature is connected or while booting from RAM or system memory bootloader. A bus error is generated in case of read request.
- When booting from Flash memory, accesses (read, erase, program) to Flash memory from user code are allowed.

When Level 1 is active, programming the protection option byte (RDP) to Level 0 causes the Flash memory to be mass-erased. As a result the user code area is cleared before the read protection is removed. The mass erase only erases the user code area. The other option bytes including write protections remain unchanged from before the mass-erase operation. The OTP area is not affected by mass erase and remains unchanged. Mass erase is performed only when Level 1 is active and Level 0 requested. When the protection level is increased (0->1, 1->2, 0->2) there is no mass erase.

- Level 2: debug/chip read protection disabled

The read protection Level 2 is activated by writing 0xCC to the RDP option byte. When the read protection Level 2 is set:

- All protections provided by Level 1 are active.
- Booting from RAM or system memory bootloader is no more allowed.
- JTAG, SWV (single-wire viewer), ETM, and boundary scan are disabled.
- User option bytes can no longer be changed.
- When booting from Flash memory, accesses (read, erase and program) to Flash memory from user code are allowed.

Memory read protection Level 2 is an irreversible operation. When Level 2 is activated, the level of protection cannot be decreased to Level 0 or Level 1.

*Note: The JTAG port is permanently disabled when Level 2 is active (acting as a JTAG fuse). As a consequence, boundary scan cannot be performed. STMicroelectronics is not able to perform analysis on defective parts on which the Level 2 protection has been set.*

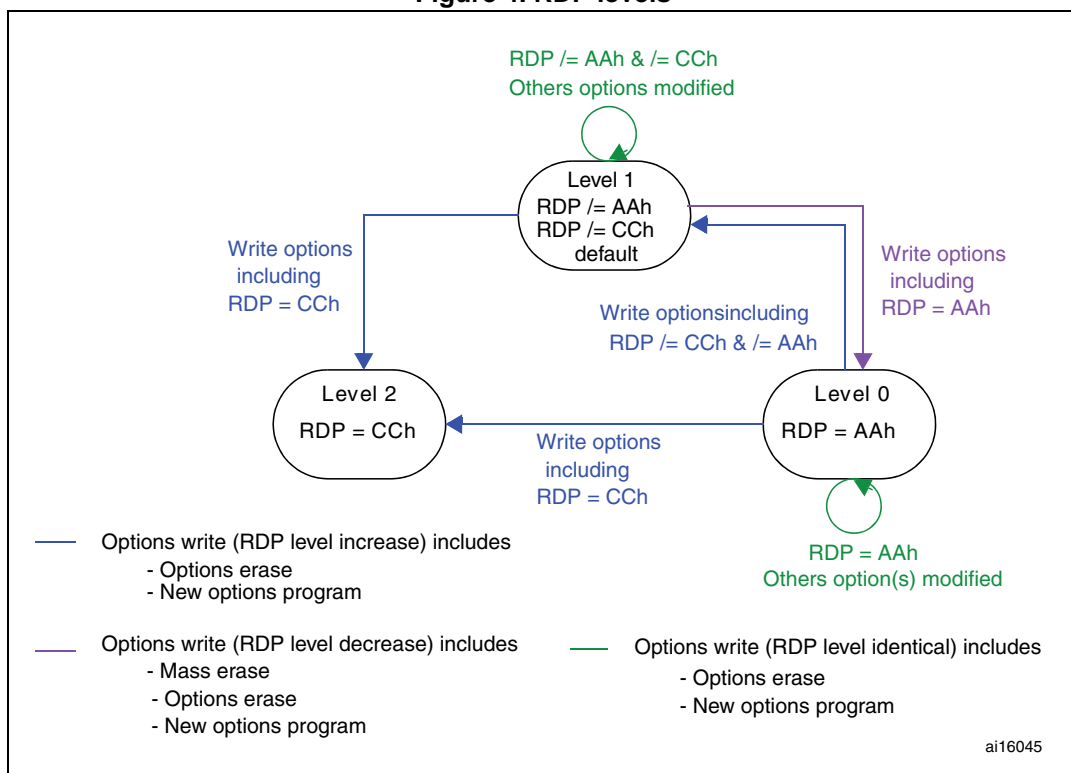
Table 11. Access versus read protection level

Memory area	Protection Level	Debug features, Boot from RAM or from System memory bootloader			Booting from Flash memory		
		Read	Write	Erase	Read	Write	Erase
Main Flash Memory	Level 1	NO		NO <sup>(1)</sup>	YES		
	Level 2	NO			YES		
Option Bytes	Level 1	YES			YES		
	Level 2	NO			NO		
OTP	Level 1	NO		NA	YES		NA
	Level 2	NO		NA	YES		NA

1. The main Flash memory is only erased when the RDP changes from level 1 to 0. The OTP area remains unchanged.

Figure 4 shows how to go from one RDP level to another.

Figure 4. RDP levels



### 3.6.4 Write protections

Up to 5 (STM32F401xB/C) or up to 7 (STM32F401xD/E) user sectors in Flash memory can be protected against unwanted write operations due to loss of program counter contexts. When the non-write protection nWRP<sub>i</sub> bit (0 ≤ i ≤ 7) in the FLASH\_OPTCR registers is low, the corresponding sector cannot be erased or programmed. Consequently, a mass erase cannot be performed if one of the sectors is write-protected.

If an erase/program operation to a write-protected part of the Flash memory is attempted (sector protected by write protection bit, OTP part locked or part of the Flash memory that can never be written like the ICP), the write protection error flag (WRPERR) is set in the FLASH\_SR register.

*Note:* When the memory read protection level is selected (RDP level = 1), it is not possible to program or erase Flash memory sector *i* if the CPU debug features are connected (JTAG or single wire) or boot code is being executed from RAM, even if  $nWRP_i = 1$ .

### Write protection error flag

If an erase/program operation to a write protected area of the Flash memory is performed, the Write Protection Error flag (WRPERR) is set in the FLASH\_SR register.

If an erase operation is requested, the WRPERR bit is set when:

- Mass, bank, sector erase are configured (MER and SER = 1)
- A sector erase is requested and the Sector Number SNB field is not valid
- A mass erase is requested while at least one of the user sector is write protected by option bit (MER = 1 and  $nWRP_i = 0$  with  $0 \leq i \leq 7$  bits in the FLASH\_OPTCRx register)
- A sector erase is requested on a write protected sector. (SER = 1, SNB = *i* and  $nWRP_i = 0$  with  $0 \leq i \leq 7$  bits in the FLASH\_OPTCRx register)
- The Flash memory is readout protected and an intrusion is detected.

If a program operation is requested, the WRPERR bit is set when:

- A write operation is performed on system memory or on the reserved part of the user specific sector.
- A write operation is performed to the user configuration sector
- A write operation is performed on a sector write protected by option bit.
- A write operation is requested on an OTP area which is already locked
- The Flash memory is read protected and an intrusion is detected.

### 3.6.5 Proprietary code readout protection (PCROP)

Flash memory user sectors (0 to 5 for STM32F401xB/C) or up to 7 for STM32F401xD/E) can be protected against D-bus read accesses by using the proprietary readout protection (PCROP).

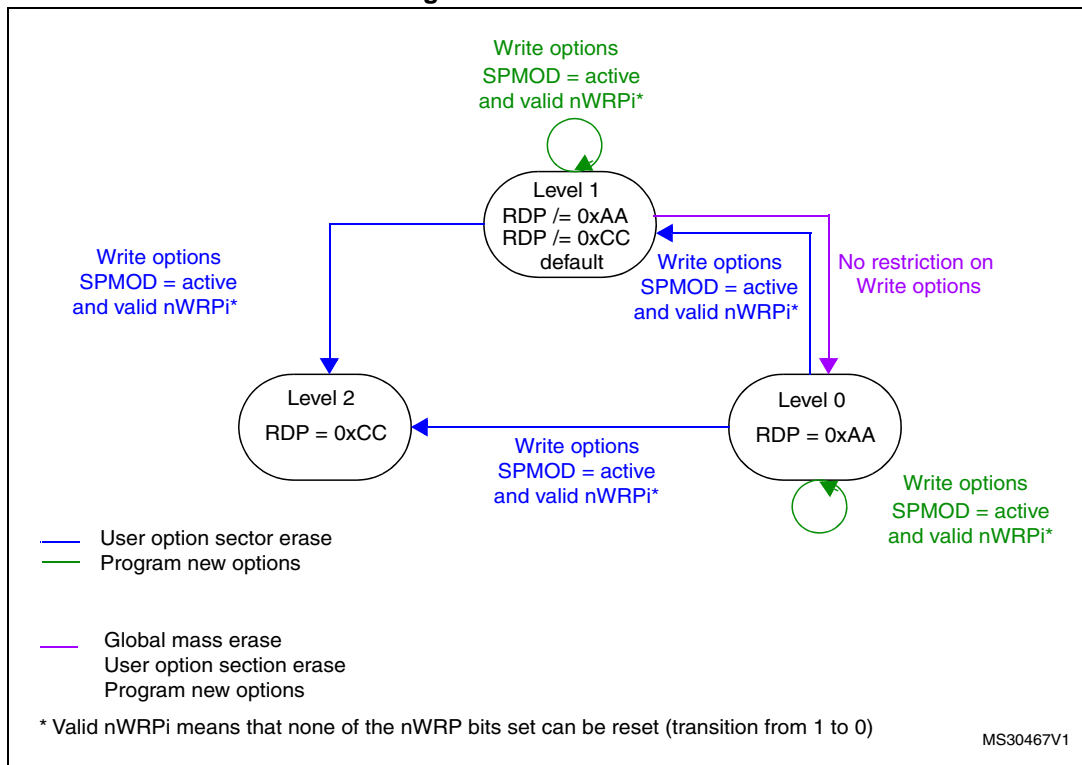
The PCROP protection is selected as follows, through the SPRMOD option bit in the FLASH\_CR register:

- SPRMOD = 0:  $nWRP_i$  control the write protection of respective user sectors
- SPRMOD = 1:  $nWRP_i$  control the read and write protection (PCROP) of respective user sectors.

When a sector is readout protected (PCROP mode activated), it can only be accessed for code fetch through ICODE Bus on Flash interface:

- Any read access performed through the D-bus triggers a RDERR flag error.
- Any program/erase operation on a PCROPed sector triggers a WRPERR flag error.

Figure 5. PCROP levels



The deactivation of the SPRMOD and/or the unprotection of PCROPed user sectors can only occur when, at the same time, the RDP level changes from 1 to 0. If this condition is not respected, the user option byte modification is cancelled and the write error WRPERR flag is set. The modification of the users option bytes (BOR\_LEV, RST\_STDBY, ..) is allowed since none of the active nWRP<sub>i</sub> bits is reset and SPRMOD is kept active.

*Note:* The active value of nWRP<sub>i</sub> bits is inverted when PCROP mode is active (SPRMOD = 1).  
If SPRMOD = 1 and nWRP<sub>i</sub> = 1, then user sector i of bank 1, respectively bank 2 is read/write protected (PCROP).

### 3.7 One-time programmable bytes

*Table 12* shows the organization of the one-time programmable (OTP) part of the OTP area.

**Table 12. OTP area organization**

Block	[128:96]	[95:64]	[63:32]	[31:0]	Address byte 0
0	OTP0	OTP0	OTP0	OTP0	0x1FFF 7800
	OTP0	OTP0	OTP0	OTP0	0x1FFF 7810
1	OTP1	OTP1	OTP1	OTP1	0x1FFF 7820
	OTP1	OTP1	OTP1	OTP1	0x1FFF 7830
·		·			·
·		·			·
·		·			·
15	OTP15	OTP15	OTP15	OTP15	0x1FFF 79E0
	OTP15	OTP15	OTP15	OTP15	0x1FFF 79F0
Lock block	LOCKB15 ... LOCKB12	LOCKB11 ... LOCKB8	LOCKB7 ... LOCKB4	LOCKB3 ... LOCKB0	0x1FFF 7A00

The OTP area is divided into 16 OTP data blocks of 32 bytes and one lock OTP block of 16 bytes. The OTP data and lock blocks cannot be erased. The lock block contains 16 bytes LOCKBi ( $0 \leq i \leq 15$ ) to lock the corresponding OTP data block (blocks 0 to 15). Each OTP data block can be programmed until the value 0x00 is programmed in the corresponding OTP lock byte. The lock bytes must only contain 0x00 and 0xFF values, otherwise the OTP bytes might not be taken into account correctly.



### 3.8 Flash interface registers

#### 3.8.1 Flash access control register (FLASH\_ACR)

The Flash access control register is used to enable/disable the acceleration features and control the Flash memory access time according to CPU frequency.

Address offset: 0x00

Reset value: 0x0000 0000

Access: no wait state, word, half-word and byte access

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	
Reserved																
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
Reserved			DCRST	ICRST	DCEN	ICEN	PRFTEN	Reserved					LATENCY			
			rw	w	rw	rw	rw						rw	rw	rw	rw

Bits 31:13 Reserved, must be kept cleared.

Bit 12 **DCRST**: Data cache reset

0: Data cache is not reset

1: Data cache is reset

This bit can be written only when the D cache is disabled.

Bit 11 **ICRST**: Instruction cache reset

0: Instruction cache is not reset

1: Instruction cache is reset

This bit can be written only when the I cache is disabled.

Bit 10 **DCEN**: Data cache enable

0: Data cache is disabled

1: Data cache is enabled

Bit 9 **ICEN**: Instruction cache enable

0: Instruction cache is disabled

1: Instruction cache is enabled

Bit 8 **PRFTEN**: Prefetch enable

0: Prefetch is disabled

1: Prefetch is enabled

Bits 7:4 Reserved, must be kept cleared.

Bits 3:0 **LATENCY**: Latency

These bits represent the ratio of the CPU clock period to the Flash memory access time.

0000: Zero wait state

0001: One wait state

0010: Two wait states

-

-

-

1110: Fourteen wait states

1111: Fifteen wait states

### 3.8.2 Flash key register (FLASH\_KEYR)

The Flash key register is used to allow access to the Flash control register and so, to allow program and erase operations.

Address offset: 0x04

Reset value: 0x0000 0000

Access: no wait state, word access

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
KEY[31:16]															
w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
KEY[15:0]															
w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w

Bits 31:0 **FKEYR**: FPEC key

The following values must be programmed consecutively to unlock the FLASH\_CR register and allow programming/erasing it:

- a) KEY1 = 0x45670123
- b) KEY2 = 0xCDEF89AB

### 3.8.3 Flash option key register (FLASH\_OPTKEYR)

The Flash option key register is used to allow program and erase operations in the user configuration sector.

Address offset: 0x08

Reset value: 0x0000 0000

Access: no wait state, word access

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
OPTKEYR[31:16]															
w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
OPTKEYR[15:0]															
w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w

Bits 31:0 **OPTKEYR**: Option byte key

The following values must be programmed consecutively to unlock the FLASH\_OPTCR register and allow programming it:

- a) OPTKEY1 = 0x08192A3B
- b) OPTKEY2 = 0x4C5D6E7F

### 3.8.4 Flash status register (FLASH\_SR)

The Flash status register gives information on ongoing program and erase operations.

Address offset: 0x0C

Reset value: 0x0000 0000

Access: no wait state, word, half-word and byte access

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved															BSY
															r
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved							RDERR	PGSERR	PGPERR	PGAERR	WRPERR	Reserved		OPERR	EOP
							rw	rc_w1	rc_w1	rc_w1	rc_w1			rc_w1	rc_w1

Bits 31:17 Reserved, must be kept cleared.

Bit 16 **BSY**: Busy

This bit indicates that a Flash memory operation is in progress. It is set at the beginning of a Flash memory operation and cleared when the operation finishes or an error occurs.

0: no Flash memory operation ongoing

1: Flash memory operation ongoing

Bits 15:9 Reserved, must be kept cleared.

Bit 8 **RDERR**: Read Protection Error (pcrop)

Set by hardware when an address to be read through the Dbus belongs to a read protected part of the flash.

Reset by writing 1.

Bit 7 **PGSERR**: Programming sequence error

Set by hardware when a write access to the Flash memory is performed by the code while the control register has not been correctly configured.

Cleared by writing 1.

Bit 6 **PGPERR**: Programming parallelism error

Set by hardware when the size of the access (byte, half-word, word, double word) during the program sequence does not correspond to the parallelism configuration PSIZE (x8, x16, x32, x64).

Cleared by writing 1.

Bit 5 **PGAERR**: Programming alignment error

Set by hardware when the data to program cannot be contained in the same 128-bit Flash memory row.

Cleared by writing 1.

Bit 4 **WRPERR**: Write protection error

Set by hardware when an address to be erased/programmed belongs to a write-protected part of the Flash memory.

Cleared by writing 1.

Bits 3:2 Reserved, must be kept cleared.

Bit 1 **OPERR**: Operation error

Set by hardware when a flash operation (programming / erase /read) request is detected and can not be run because of parallelism, alignment, or write protection error. This bit is set only if error interrupts are enabled (ERRIE = 1).

Bit 0 **EOP**: End of operation

Set by hardware when one or more Flash memory operations (program/erase) has/have completed successfully. It is set only if the end of operation interrupts are enabled (EOPIE = 1).  
Cleared by writing a 1.

### 3.8.5 Flash control register (FLASH\_CR)

The Flash control register is used to configure and start Flash memory operations.

Address offset: 0x10

Reset value: 0x8000 0000

Access: no wait state when no Flash memory operation is ongoing, word, half-word and byte access.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
LOCK	Reserved					ERRIE	EOPIE	Reserved							STRT
rs						rw	rw								rs
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved						PSIZE[1:0]		Res.	SNB[3:0]				MER	SER	PG
						rw	rw		rw	rw	rw	rw	rw	rw	rw

Bit 31 **LOCK**: Lock

Write to 1 only. When it is set, this bit indicates that the FLASH\_CR register is locked. It is cleared by hardware after detecting the unlock sequence.  
In the event of an unsuccessful unlock operation, this bit remains set until the next reset.

Bits 30:26 Reserved, must be kept cleared.

Bit 25 **ERRIE**: Error interrupt enable

This bit enables the interrupt generation when the OPERR bit in the FLASH\_SR register is set to 1.

0: Error interrupt generation disabled

1: Error interrupt generation enabled

Bit 24 **EOPIE**: End of operation interrupt enable

This bit enables the interrupt generation when the EOP bit in the FLASH\_SR register goes to 1.

0: Interrupt generation disabled

1: Interrupt generation enabled

Bits 23:17 Reserved, must be kept cleared.

Bit 16 **STRT**: Start

This bit triggers an erase operation when set. It is set only by software and cleared when the BSY bit is cleared.

Bits 15:10 Reserved, must be kept cleared.

Bits 9:8 **PSIZE**: Program size

These bits select the program parallelism.

00 program x8

01 program x16

10 program x32

11 program x64

Bit 7 Reserved, must be kept cleared.

Bits 6:3 **SNB**: Sector number

These bits select the sector to erase.

0000 sector 0

0001 sector 1

...

0101 sector 5

0110 sector 6 (STM32F401xD/E devices only)

0111 sector 7 (STM32F401xE devices only)

1000 not allowed

...

1011 not allowed

1100 user specific sector

1101 user configuration sector

1110 not allowed

1111 not allowed

Bit 2 **MER**: Mass Erase

Erase activated for all user sectors.

Bit 1 **SER**: Sector Erase

Sector Erase activated.

Bit 0 **PG**: Programming

Flash programming activated.

### 3.8.6 Flash option control register (FLASH\_OPTCR)

The FLASH\_OPTCR register is used to modify the user option bytes.

Address offset: 0x14

Reset value: 0x0FFF AAED. The option bits are loaded with values from Flash memory at reset release.

Access: no wait state when no Flash memory operation is ongoing, word, half-word and byte access.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16		
SPR MOD	Reserved							nWRP[7:6] <sup>(1)</sup>		nWRP[5:0]							
rw								rw	rw	rw	rw	rw	rw	rw	rw	rw	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0		
RDP[7:0]								nRST_STDBY	nRST_STOP	WDG_SW	Reserved	BOR_LEV		OPTSTRT	OPTLOCK		
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw		rw	rw	rs	rs		

1. Available in STM32F401xD/E devices only

Bit 31 **SPRMOD**: Selection of Protection Mode of nWPRi bits

0: PCROP disabled, nWPRi bits used for Write Protection on sector i

1: PCROP enabled, nWPRi bits used for PCROP Protection on sector i

Bits 30:24 **Reserved**, must be kept cleared.

Bits 23:22 **nWRP[7:6]**: Not write protect

For STM32F401xB/C:

Reserved, must be kept cleared.

For STM32F401xD/E:

These bits contain the value of the write-protection and read-protection (PCROP) option bytes for sectors 6 and 7 after reset. (Refer to Bits 21:16 for more details)

Bits 21:16 **nWRP[5:0]**: Not write protect

These bits contain the value of the write-protection option bytes of sectors after reset. They can be written to program a new write protect value into Flash memory.

0: Write protection active on selected sector

1: Write protection not active on selected sector

These bits contain the value of the write-protection and read-protection (PCROP) option bytes for sectors 0 to 5 after reset. They can be written to program a new write-protect or PCROP value into Flash memory.

If SPRMOD is reset:

0: Write protection active on sector i

1: Write protection not active on sector i

If SPRMOD is set:

0: PCROP protection not active on sector i

1: PCROP protection active on sector i

Bits 15:8 **RDP**: Read protect

These bits contain the value of the read-protection option level after reset. They can be written to program a new read protection value into Flash memory.

0xAA: Level 0, read protection not active

0xCC: Level 2, chip read protection active

Others: Level 1, read protection of memories active

**Bits 7:5 USER:** User option bytes

These bits contain the value of the user option byte after reset. They can be written to program a new user option byte value into Flash memory.

Bit 7: nRST\_STDBY

Bit 6: nRST\_STOP

Bit 5: WDG\_SW

*Note:* When changing the WDG mode from hardware to software or from software to hardware, a system reset is required to make the change effective.

Bit 4 Reserved, must be kept cleared. Always read as "0".

**Bits 3:2 BOR\_LEV:** BOR reset Level

These bits contain the supply level threshold that activates/releases the reset. They can be written to program a new BOR level. By default, BOR is off. When the supply voltage ( $V_{DD}$ ) drops below the selected BOR level, a device reset is generated.

00: BOR Level 3 (VBOR3), brownout threshold level 3

01: BOR Level 2 (VBOR2), brownout threshold level 2

10: BOR Level 1 (VBOR1), brownout threshold level 1

11: BOR off, POR/PDR reset threshold level is applied

*Note:* For full details about BOR characteristics, refer to the "Electrical characteristics" section in the device datasheet.

**Bit 1 OPTSTRT:** Option start

This bit triggers a user option operation when set. It is set only by software and cleared when the BSY bit is cleared.

**Bit 0 OPTLOCK:** Option lock

Write to 1 only. When this bit is set, it indicates that the FLASH\_OPTCR register is locked.

This bit is cleared by hardware after detecting the unlock sequence.

In the event of an unsuccessful unlock operation, this bit remains set until the next reset.

3.8.7 Flash interface register map

Table 13. Flash register map and reset values

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0x00	FLASH_ACR	Reserved																			DCRST	ICRST	DCEN	ICEN	PRFTEN	Reserved				LATENCY			
	Reset value																				0	0	0	0	0					0	0	0	0
0x04	FLASH_KEYR	KEY[31:16]														KEY[15:0]																	
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	
0x08	FLASH_OPTKEYR	OPTKEYR[31:16]														OPTKEYR[15:0]																	
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	
0x0C	FLASH_SR	Reserved														BSY	Reserved							RDERR	PGSERR	PGPERR	PGAERR	WRPERR	Reserved		OPERR	EOP	
	Reset value															0								0	0	0	0	0			0	0	
0x10	FLASH_CR	LOCK	Reserved				ERRIE	EOPIE	Reserved				STRT	Reserved				PSIZE[1:0]		Reserved		SNB[3:0]			MER	SER	PG						
	Reset value	1					0	0					0					0	0	0			0	0	0								
0x14	FLASH_OPTCR	SPRMOD	Reserved				nWRP[7:0]				RDP[7:0]				nRST_STDBY	nRST_STOP	WDG_SW	Reserved		BOR_LEV		OPTSTRT	OPTLOCK										
	Reset value	0					1	1	1	1	1	1	1	1	1	1	0	1	0	1	0	1	0	1	0								



## 4 CRC calculation unit

### 4.1 CRC introduction

The CRC (cyclic redundancy check) calculation unit is used to get a CRC code from a 32-bit data word and a fixed generator polynomial.

Among other applications, CRC-based techniques are used to verify data transmission or storage integrity. In the scope of the EN/IEC 60335-1 standard, they offer a means of verifying the Flash memory integrity. The CRC calculation unit helps compute a signature of the software during runtime, to be compared with a reference signature generated at link-time and stored at a given memory location.

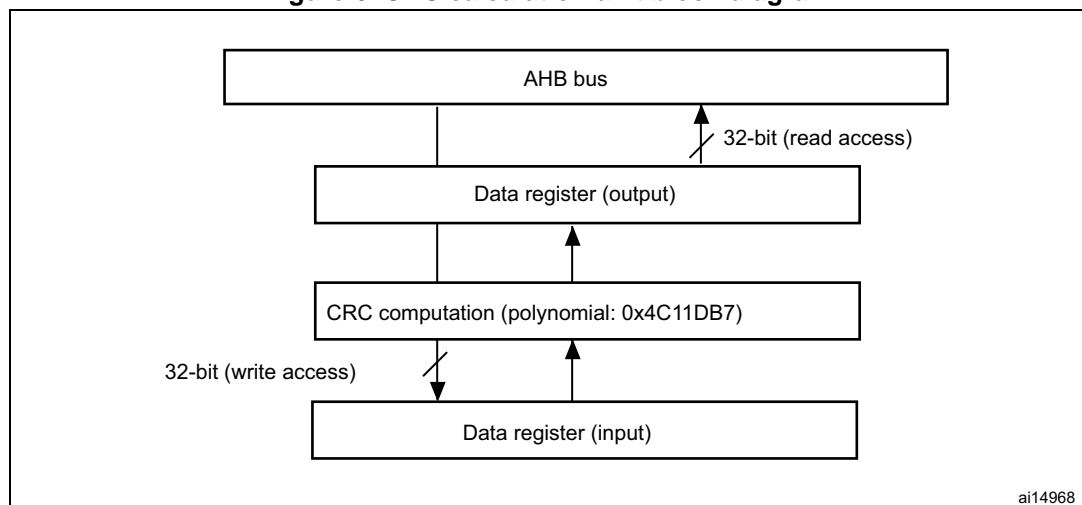
### 4.2 CRC main features

- Uses CRC-32 (Ethernet) polynomial:  $0x4C11DB7$   

$$- X^{32} + X^{26} + X^{23} + X^{22} + X^{16} + X^{12} + X^{11} + X^{10} + X^8 + X^7 + X^5 + X^4 + X^2 + X + 1$$
- Single input/output 32-bit data register
- CRC computation done in 4 AHB clock cycles (HCLK)
- General-purpose 8-bit register (can be used for temporary storage)

The block diagram is shown in [Figure 6](#).

**Figure 6. CRC calculation unit block diagram**



### 4.3 CRC functional description

The CRC calculation unit mainly consists of a single 32-bit data register, which:

- is used as an input register to enter new data in the CRC calculator (when writing into the register)
- holds the result of the previous CRC calculation (when reading the register)

Each write operation into the data register creates a combination of the previous CRC value and the new one (CRC computation is done on the whole 32-bit data word, and not byte per byte).

The write operation is stalled until the end of the CRC computation, thus allowing back-to-back write accesses or consecutive write and read accesses.

The CRC calculator can be reset to 0xFFFF FFFF with the RESET control bit in the CRC\_CR register. This operation does not affect the contents of the CRC\_IDR register.

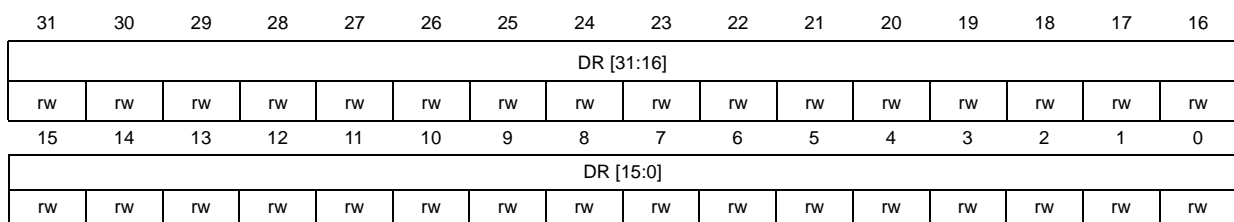
## 4.4 CRC registers

The CRC calculation unit contains two data registers and a control register. *The peripheral*  
The CRC registers have to be accessed by words (32 bits).

### 4.4.1 Data register (CRC\_DR)

Address offset: 0x00

Reset value: 0xFFFF FFFF



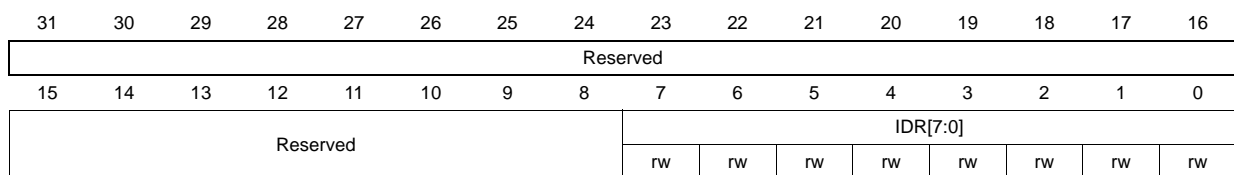
**Bits 31:0 Data register bits**

Used as an input register when writing new data into the CRC calculator.  
Holds the previous CRC calculation result when it is read.

### 4.4.2 Independent data register (CRC\_IDR)

Address offset: 0x04

Reset value: 0x0000 0000



Bits 31:8 Reserved, must be kept at reset value.

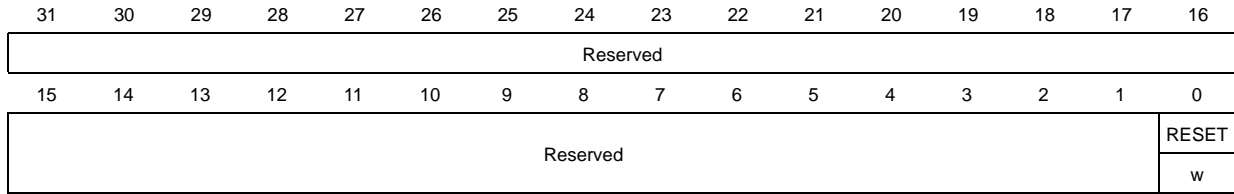
**Bits 7:0 General-purpose 8-bit data register bits**

Can be used as a temporary storage location for one byte.  
This register is not affected by CRC resets generated by the RESET bit in the CRC\_CR register.

### 4.4.3 Control register (CRC\_CR)

Address offset: 0x08

Reset value: 0x0000 0000



Bits 31:1 Reserved, must be kept at reset value.

**Bit 0 RESET bit**

Resets the CRC calculation unit and sets the data register to 0xFFFF FFFF.  
This bit can only be set, it is automatically cleared by hardware.

### 4.4.4 CRC register map

The following table provides the CRC register map and reset values.

**Table 14. CRC calculation unit register map and reset values**

Offset	Register	31-24	23-16	15-8	7	6	5	4	3	2	1	0
0x00	<b>CRC_DR</b>	Data register										
	Reset value	0xFFFF FFFF										
0x04	<b>CRC_IDR</b>	Reserved			Independent data register							
	Reset value				0x00							
0x08	<b>CRC_CR</b>	Reserved										RESET
	Reset value											0

## 5 Power controller (PWR)

### 5.1 Power supplies

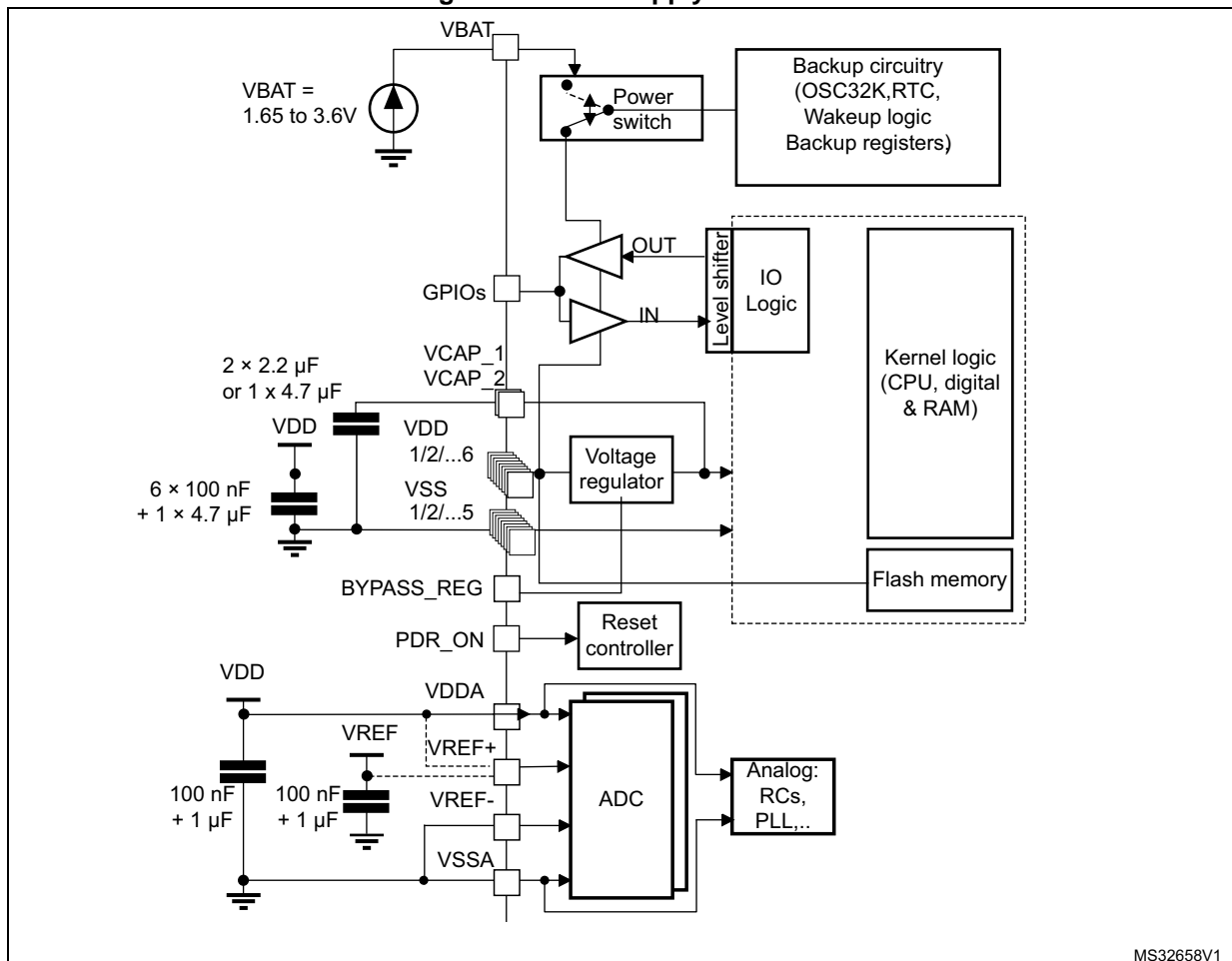
There are two main power supply schemes:

- VDD = 1.7 to 3.6 V: external power supply for I/Os with the internal regulator disabled, provided externally through VDD pins. Requires the use of an external power supply supervisor connected to the VDD and PDR\_ON pins.
- VDD = 1.8 to 3.6 V: external power supply for I/Os and the internal regulator (when enabled), provided externally through VDD pins.

The real-time clock (RTC) and the RTC backup registers can be powered from the V<sub>BAT</sub> voltage when the main V<sub>DD</sub> supply is powered off.

*Note: Depending on the operating power supply range, some peripheral may be used with limited functionality and performance. For more details refer to section "General operating conditions" in STM32F4xx datasheets.*

**Figure 7. Power supply overview**



1. V<sub>DDA</sub> and V<sub>SSA</sub> must be connected to V<sub>DD</sub> and V<sub>SS</sub>, respectively.

### 5.1.1 Independent A/D converter supply and reference voltage

To improve conversion accuracy, the ADC has an independent power supply which can be separately filtered and shielded from noise on the PCB.

- The ADC voltage supply input is available on a separate  $V_{DDA}$  pin.
- An isolated supply ground connection is provided on pin  $V_{SSA}$ .

To ensure a better accuracy of low voltage inputs, the user can connect a separate external reference voltage ADC input on  $V_{REF}$ . The voltage on  $V_{REF}$  ranges from 1.7 V to  $V_{DDA}$ .

### 5.1.2 Battery backup domain

#### Backup domain description

To retain the content of the RTC backup registers and supply the RTC when  $V_{DD}$  is turned off,  $V_{BAT}$  pin can be connected to an optional standby voltage supplied by a battery or by another source.

To allow the RTC to operate even when the main digital supply ( $V_{DD}$ ) is turned off, the  $V_{BAT}$  pin powers the following blocks:

- The RTC
- The LSE oscillator
- PC13 to PC15 I/Os

The switch to the  $V_{BAT}$  supply is controlled by the power-down reset embedded in the Reset block.

---

**Warning:** During  $t_{RSTTEMPO}$  (temporization at  $V_{DD}$  startup) or after a PDR is detected, the power switch between  $V_{BAT}$  and  $V_{DD}$  remains connected to  $V_{BAT}$ .  
 During the startup phase, if  $V_{DD}$  is established in less than  $t_{RSTTEMPO}$  (Refer to the datasheet for the value of  $t_{RSTTEMPO}$ ) and  $V_{DD} > V_{BAT} + 0.6$  V, a current may be injected into  $V_{BAT}$  through an internal diode connected between  $V_{DD}$  and the power switch ( $V_{BAT}$ ).  
 If the power supply/battery connected to the  $V_{BAT}$  pin cannot support this current injection, it is strongly recommended to connect an external low-drop diode between this power supply and the  $V_{BAT}$  pin.

---

If no external battery is used in the application, it is recommended to connect the  $V_{BAT}$  pin to  $V_{DD}$  with a 100 nF external decoupling ceramic capacitor in parallel.

When the backup domain is supplied by  $V_{DD}$  (analog switch connected to  $V_{DD}$ ), the following functions are available:

- PC14 and PC15 can be used as either GPIO or LSE pins
- PC13 can be used as a GPIO or additional functions can be configured (refer to [Table 26: RTC additional functions](#) for more details about this pin configuration)

*Note:* Due to the fact that the switch only sinks a limited amount of current (3 mA), the use of PC13 to PC15 GPIOs in output mode is restricted: the speed has to be limited to 2 MHz with

a maximum load of 30 pF and these I/Os must not be used as a current source (e.g. to drive an LED).

When the backup domain is supplied by  $V_{BAT}$  (analog switch connected to  $V_{BAT}$  because  $V_{DD}$  is not present), the following functions are available:

- PC14 and PC15 can be used as LSE pins only
- PC13 can be used as the RTC additional function pin (refer to [Table 26: RTC additional functions](#) for more details about this pin configuration)

### Backup domain access

After reset, the backup domain (RTC registers and RTC backup register) is protected against possible unwanted write accesses. To enable access to the backup domain, proceed as follows:

- Access to the RTC and RTC backup registers
  1. Enable the power interface clock by setting the PWREN bits in the RCC\_APB1ENR register (see [Section 6.3.11: RCC APB1 peripheral clock enable register \(RCC\\_APB1ENR\)](#))
  2. Set the DBP bit in the [Section 5.4.1](#) to enable access to the backup domain
  3. Select the RTC clock source: see [Section 6.2.8: RTC/AWU clock](#)
  4. Enable the RTC clock by programming the RTCEN [15] bit in the [Section 6.3.17: RCC Backup domain control register \(RCC\\_BDCR\)](#)

### RTC and RTC backup registers

The real-time clock (RTC) is an independent BCD timer/counter. The RTC provides a time-of-day clock/calendar, two programmable alarm interrupts, and a periodic programmable wakeup flag with interrupt capability. The RTC contains 20 backup data registers (80 bytes) which are reset when a tamper detection event occurs. For more details refer to [Section 17: Real-time clock \(RTC\)](#).

## 5.1.3 Voltage regulator

An embedded linear voltage regulator supplies all the digital circuitries except for the backup domain and the Standby circuitry. The regulator output voltage is around 1.2 V.

This voltage regulator requires one or two external capacitors to be connected to one or two dedicated pins,  $V_{CAP\_1}$  and for some packages  $V_{CAP\_2}$ . Specific pins must be connected either to  $V_{SS}$  or  $V_{DD}$  to activate or deactivate the voltage regulator. These pins depend on the package.

When activated by software, the voltage regulator is always enabled after Reset. It works in three different modes depending on the application modes.

- In **Run mode**, the regulator supplies full power to the 1.2 V domain (core, memories and digital peripherals). In this mode, the regulator output voltage (around 1.2 V) can be scaled by software to different voltage values:
  - Scale 2, or scale 3 can be configured through the VOS[1:0] bits of the PWR\_CR register (scale 1 is not used in this product). After reset the VOS register is set to scale 2. When the PLL is OFF, the voltage regulator is set to scale 3 independently

of the VOS register content. The VOS register content is only taken into account once the PLL is activated and the HSI or HSE is selected as clock source.

The voltage scaling allows optimizing the power consumption when the device is clocked below the maximum system frequency.

- In **Stop mode**, the main regulator or the low-power regulator supplies low power to the 1.2 V domain, thus preserving the content of registers and internal SRAM. The voltage regulator can be put either in main regulator mode (MR) or in low-power mode (LPR). The programmed voltage scale remains the same during Stop mode:

Voltage scale 3 is automatically selected when the microcontroller enters Stop mode (see [Section 5.4.1: PWR power control register \(PWR\\_CR\)](#)).

- In **Standby mode**, the regulator is powered down. The content of the registers and SRAM are lost except for the Standby circuitry and the backup domain.

*Note:* For more details, refer to the voltage regulator section in the STM32F401xB/C datasheet.

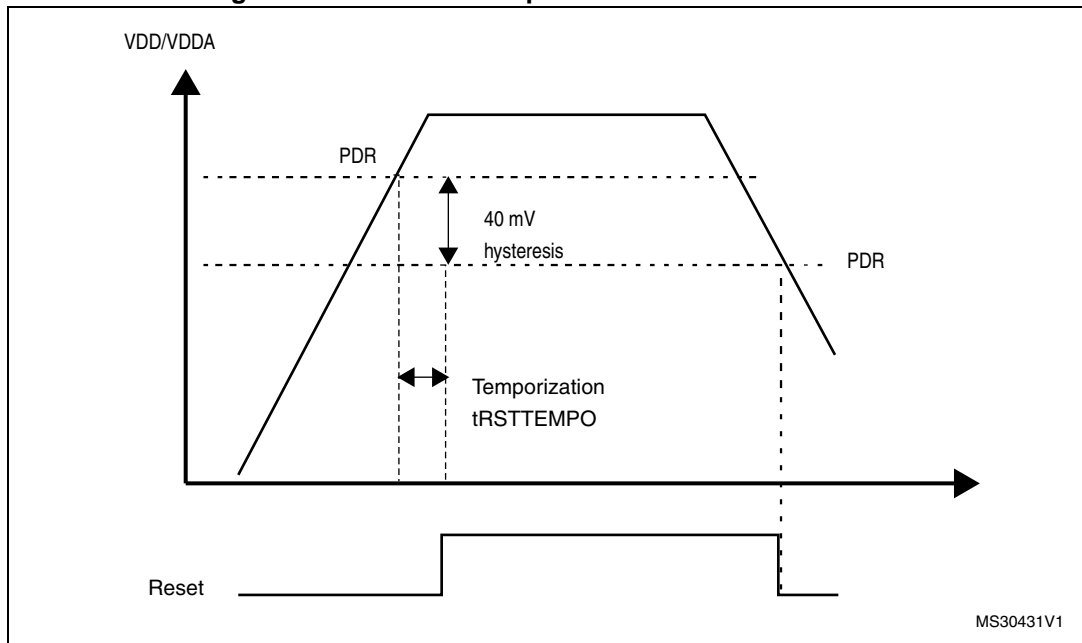
## 5.2 Power supply supervisor

### 5.2.1 Power-on reset (POR)/power-down reset (PDR)

The device has an integrated POR/PDR circuitry that allows proper operation starting from 1.8 V.

To use the device below 1.8 V, the internal power supervisor must be switched off using the PDR\_ON pin (please refer to section Power supply supervisor of the STM32F401xB/C datasheet). The device remains in Reset mode when  $V_{DD}/V_{DDA}$  is below a specified threshold,  $V_{POR/PDR}$ , without the need for an external reset circuit. For more details concerning the power on/power-down reset threshold, refer to the electrical characteristics of the datasheet.

Figure 8. Power-on reset/power-down reset waveform



### 5.2.2 Brownout reset (BOR)

During power on, the Brownout reset (BOR) keeps the device under reset until the supply voltage reaches the specified  $V_{BOR}$  threshold.

$V_{BOR}$  is configured through device option bytes. By default, BOR is off. 3 programmable  $V_{BOR}$  threshold levels can be selected:

- BOR Level 3 (VBOR3). Brownout threshold level 3.
- BOR Level 2 (VBOR2). Brownout threshold level 2.
- BOR Level 1 (VBOR1). Brownout threshold level 1.

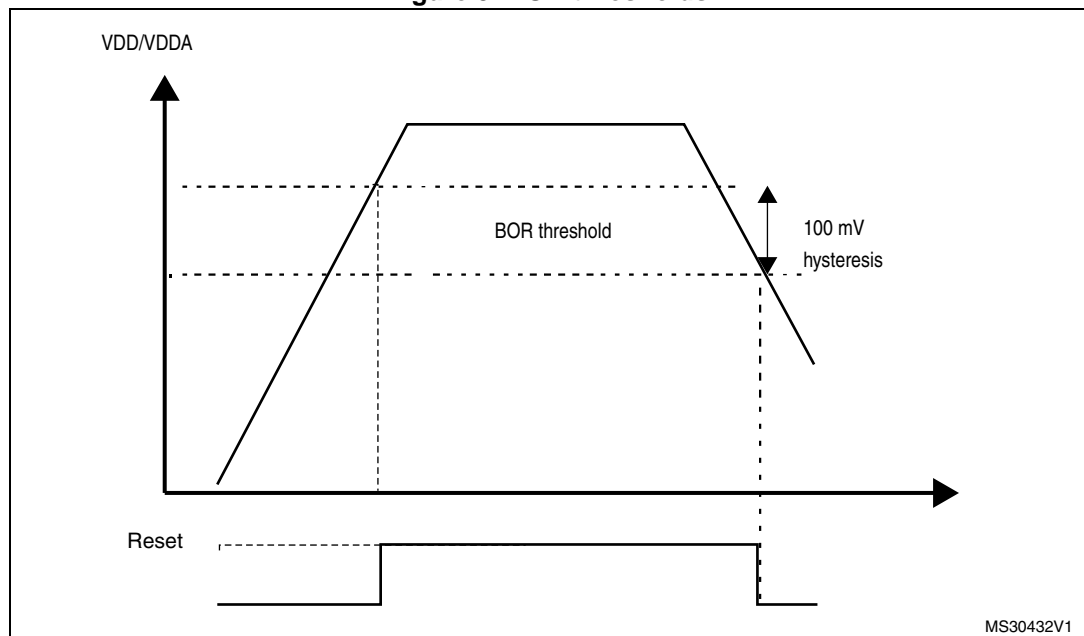
*Note:* For full details about BOR characteristics, refer to the "Electrical characteristics" section in the device datasheet.

When the supply voltage ( $V_{DD}$ ) drops below the selected  $V_{BOR}$  threshold, a device reset is generated.

The BOR can be disabled by programming the device option bytes. In this case, the power-on and power-down is then monitored by the POR/ PDR or by an external power supervisor if the PDR is switched off through the PDR\_ON pin (see [Section 5.2.1: Power-on reset \(POR\)/power-down reset \(PDR\)](#)).

The BOR threshold hysteresis is ~100 mV (between the rising and the falling edge of the supply voltage).

**Figure 9. BOR thresholds**





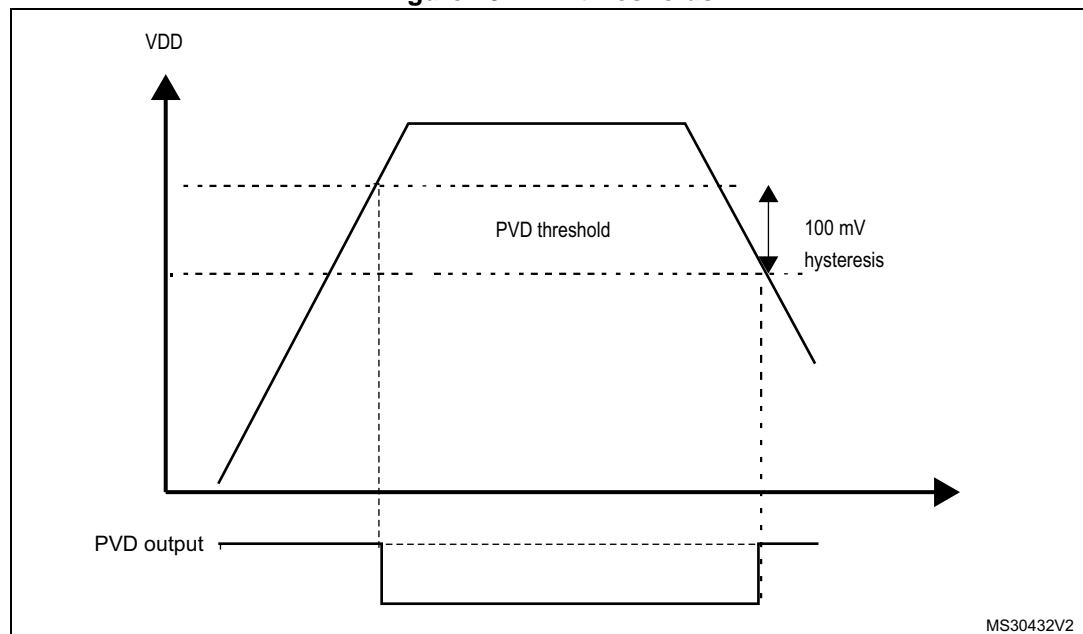
### 5.2.3 Programmable voltage detector (PVD)

You can use the PVD to monitor the  $V_{DD}$  power supply by comparing it to a threshold selected by the PLS[2:0] bits in the *PWR power control register (PWR\_CR)*.

The PVD is enabled by setting the PVDE bit.

A PVDO flag is available, in the *PWR power control/status register (PWR\_CSR)*, to indicate if  $V_{DD}$  is higher or lower than the PVD threshold. This event is internally connected to the EXTI line16 and can generate an interrupt if enabled through the EXTI registers. The PVD output interrupt can be generated when  $V_{DD}$  drops below the PVD threshold and/or when  $V_{DD}$  rises above the PVD threshold depending on EXTI line16 rising/falling edge configuration. As an example the service routine could perform emergency shutdown tasks.

Figure 10. PVD thresholds



## 5.3 Low-power modes

By default, the microcontroller is in Run mode after a system or a power-on reset. In Run mode the CPU is clocked by HCLK and the program code is executed. Several low-power modes are available to save power when the CPU does not need to be kept running, for example when waiting for an external event. It is up to the user to select the mode that gives the best compromise between low-power consumption, short startup time and available wakeup sources.

The devices feature three low-power modes:

- Sleep mode (Cortex<sup>®</sup>-M4 with FPU core stopped, peripherals kept running)
- Stop mode (all clocks are stopped)
- Standby mode (1.2 V domain powered off)

In addition, the power consumption in Run mode can be reduced by one of the following means:

- Slowing down the system clocks
- Gating the clocks to the APBx and AHBx peripherals when they are unused.

### Entering low-power mode

Low-power modes are entered by the MCU by executing the WFI (Wait For Interrupt), or WFE (Wait for Event) instructions, or when the SLEEPONEXIT bit in the Cortex<sup>®</sup>-M4 with FPU System Control register is set on Return from ISR.

### Exiting low-power mode

The MCU exits from Sleep and Stop modes low-power mode depending on the way the low-power mode was entered:

- If the WFI instruction or Return from ISR was used to enter the low-power mode, any peripheral interrupt acknowledged by the NVIC can wake up the device.
- If the WFE instruction is used to enter the low-power mode, the MCU exits the low-power mode as soon as an event occurs. The wakeup event can be generated either by:
  - NVIC IRQ interrupt:

When SEVONPEND = 0 in the Cortex<sup>®</sup>-M4 with FPU System Control register: by enabling an interrupt in the peripheral control register and in the NVIC. When the MCU resumes from WFE, the peripheral interrupt pending bit and the NVIC peripheral IRQ channel pending bit (in the NVIC interrupt clear pending register) have to be cleared. Only NVIC interrupts with sufficient priority will wakeup and interrupt the MCU.

When SEVONPEND = 1 in the Cortex<sup>®</sup>-M4 with FPU System Control register: by enabling an interrupt in the peripheral control register and optionally in the NVIC. When the MCU resumes from WFE, the peripheral interrupt pending bit and when enabled the NVIC peripheral IRQ channel pending bit (in the NVIC interrupt clear pending register) have to be cleared. All NVIC interrupts will wakeup the MCU, even the disabled ones. Only enabled NVIC interrupts with sufficient priority will wakeup and interrupt the MCU.
  - Event

This is done by configuring a EXTI line in event mode. When the CPU resumes from WFE, it is not necessary to clear the EXTI peripheral interrupt pending bit or the NVIC IRQ channel pending bit as the pending bits corresponding to the event line is not set. It may be necessary to clear the interrupt flag in the peripheral.

The MCU exits from Standby low-power mode through an external reset (NRST pin), an IWDG reset, a rising edge on one of the enabled WKUPx pins or a RTC event occurs (see [Figure 159: RTC block diagram](#)).

After waking up from Standby mode, program execution restarts in the same way as after a Reset (boot pin sampling, option bytes loading, reset vector is fetched, etc.).

Only enabled NVIC interrupts with sufficient priority will wakeup and interrupt the MCU.

**Table 15. Low-power mode summary**

Mode name	Entry	Wakeup	Effect on 1.2 V domain clocks	Effect on V <sub>DD</sub> domain clocks	Voltage regulator
<b>Sleep (Sleep now or Sleep-on-exit)</b>	WFI or Return from ISR	Any interrupt	CPU CLK OFF no effect on other clocks or analog clock sources	None	ON
	WFE	Wakeup event			
<b>Stop</b>	PDDS bit + STOP mode configuration + SLEEPDEEP bit + WFI, Return from ISR or WFE	Any EXTI line (configured in the EXTI registers, internal and external lines)	All 1.2 V domain clocks OFF	HSI and HSE oscillators OFF	Main regulator or Low-Power regulator (depends on <i>PWR power control register (PWR_CR)</i> )
<b>Standby</b>	PDDS bit + SLEEPDEEP bit + WFI, Return from ISR or WFE	WKUP pin rising edge, RTC alarm (Alarm A or Alarm B), RTC Wakeup event, RTC tamper events, RTC time stamp event, external reset in NRST pin, IWDG reset			OFF

### 5.3.1 Slowing down system clocks

In Run mode the speed of the system clocks (SYSCLK, HCLK, PCLK1, PCLK2) can be reduced by programming the prescaler registers. These prescalers can also be used to slow down peripherals before entering Sleep mode.

For more details refer to [Section 6.3.3: RCC clock configuration register \(RCC\\_CFGR\)](#).

### 5.3.2 Peripheral clock gating

In Run mode, the HCLKx and PCLKx for individual peripherals and memories can be stopped at any time to reduce power consumption.

To further reduce power consumption in Sleep mode the peripheral clocks can be disabled prior to executing the WFI or WFE instructions.

Peripheral clock gating is controlled by the AHB1 peripheral clock enable register (RCC\_AHB1ENR), AHB2 peripheral clock enable register (RCC\_AHB2ENR) (see [Section 6.3.9: RCC AHB1 peripheral clock enable register \(RCC\\_AHB1ENR\)](#), [Section 6.3.10: RCC AHB2 peripheral clock enable register \(RCC\\_AHB2ENR\)](#)).

Disabling the peripherals clocks in Sleep mode can be performed automatically by resetting the corresponding bit in RCC\_AHBxLPENR and RCC\_APBxLPENR registers.

### 5.3.3 Sleep mode

#### Entering Sleep mode

The Sleep mode is entered according to [Section : Entering low-power mode](#), when the SLEEPDEEP bit in the Cortex<sup>®</sup>-M4 with FPU System Control register is cleared.

Refer to [Table 16](#) and [Table 17](#) for details on how to enter Sleep mode.

#### Exiting Sleep mode

The Sleep mode is exited according to [Section : Exiting low-power mode](#).

Refer to [Table 16](#) and [Table 17](#) for more details on how to exit Sleep mode.

**Table 16. Sleep-now entry and exit**

Sleep-now mode	Description
Mode entry	WFI (Wait for Interrupt) or WFE (Wait for Event) while: – SLEEPDEEP = 0 Refer to the Cortex <sup>®</sup> -M4 with FPU System Control register.
	On Return from ISR while: – SLEEPDEEP = 0 and – SLEEPONEXIT = 1 Refer to the Cortex <sup>®</sup> -M4 with FPU System Control register.
Mode exit	If WFI or Return from ISR was used for entry: Interrupt: Refer to <a href="#">Table 38: Vector table for STM32F401xB/CSTM32F401xD/E</a> If WFE was used for entry and SEVONPEND = 0 Wakeup event: Refer to <a href="#">Section 10.2.3: Wakeup event management</a> If WFE was used for entry and SEVONPEND = 1 Interrupt even when disabled in NVIC: refer to <a href="#">Table 38: Vector table for STM32F401xB/CSTM32F401xD/E</a> or Wakeup event (see <a href="#">Section 10.2.3: Wakeup event management</a> ).
Wakeup latency	None

**Table 17. Sleep-on-exit entry and exit**

Sleep-on-exit	Description
Mode entry	WFI (Wait for Interrupt) or WFE (Wait for Event) while: – SLEEPDEEP = 0 Refer to the Cortex <sup>®</sup> -M4 with FPU System Control register.
	On Return from ISR while: – SLEEPDEEP = 0 and – SLEEPONEXIT = 1 Refer to the Cortex <sup>®</sup> -M4 with FPU System Control register.
Mode exit	Interrupt: refer to <a href="#">Table 38: Vector table for STM32F401xB/CSTM32F401xD/E</a>
Wakeup latency	None

### 5.3.4 Stop mode

The Stop mode is based on the Cortex<sup>®</sup>-M4 with FPU deepsleep mode combined with peripheral clock gating. The voltage regulator can be configured either in normal or low-power mode. In Stop mode, all clocks in the 1.2 V domain are stopped, the PLLs, the HSI and the HSE RC oscillators are disabled. Internal SRAM and register contents are preserved.

Some settings in the PWR\_CR register allow to further reduce the power consumption. When the Flash memory is in power-down mode, an additional startup delay is incurred when waking up from Stop mode (see [Table 18: Stop operating modes](#) and [Section 5.4.1: PWR power control register \(PWR\\_CR\)](#)).

**Table 18. Stop operating modes**

	Stop mode	MRLV bit	LPLV bit	FPDS bit	LPDS bit	Wakeup latency
Normal mode	STOP MR	0	-	0	0	HSI RC startup time
	STOP MRFPD	0	-	1	0	HSI RC startup time + Flash wakeup time from Deep Power Down mode
	STOP LP	0	0	0	1	HSI RC startup time + regulator wakeup time from LP mode
	STOP LPFPD	-	0	1	1	HSI RC startup time + Flash wakeup time from Deep Power Down mode + regulator wakeup time from LP mode
	STOP MRLV	1	-	-	0	HSI RC startup time + Flash wakeup time from Deep Power Down mode + Main regulator from low voltage mode
	STOP LPLV	-	1	-	1	HSI RC startup time + Flash wakeup time from Deep Power Down mode + regulator wakeup time from Low Voltage LP mode

#### Entering Stop mode

The Stop mode is entered according to [Section : Entering low-power mode](#), when the SLEEPDEEP bit in the Cortex<sup>®</sup>-M4 with FPU System Control register is set.

Refer to [Table 19](#) for details on how to enter the Stop mode.

To further reduce power consumption in Stop mode, the internal voltage regulator can be put in low-power mode. This is configured by the LPDS bit of the [PWR power control register \(PWR\\_CR\)](#).

If Flash memory programming is ongoing, the Stop mode entry is delayed until the memory access is finished.

If an access to the APB domain is ongoing, The Stop mode entry is delayed until the APB access is finished.

In Stop mode, the following features can be selected by programming individual control bits:

- Independent watchdog (IWDG): the IWDG is started by writing to its Key register or by hardware option. Once started it cannot be stopped except by a Reset. See [Section 15.3](#) in [Section 15: Independent watchdog \(IWDG\)](#).
- Real-time clock (RTC): this is configured by the RTCEN bit in the [Section 6.3.17: RCC Backup domain control register \(RCC\\_BDCR\)](#)
- Internal RC oscillator (LSI RC): this is configured by the LSION bit in the [Section 6.3.18: RCC clock control & status register \(RCC\\_CSR\)](#).
- External 32.768 kHz oscillator (LSE OSC): this is configured by the LSEON bit in the [Section 6.3.17: RCC Backup domain control register \(RCC\\_BDCR\)](#).

The ADC can also consume power during the Stop mode, unless it is disabled before entering it. To disable it, the ADON bit in the ADC\_CR2 register must be written to 0.

*Note: If the application needs to disable the external clock before entering Stop mode, the HSEON bit must first be disabled and the system clock switched to HSI.*

*Otherwise, if the HSEON bit is kept enabled while the external clock (external oscillator) can be removed before entering stop mode, the clock security system (CSS) feature must be enabled to detect any external oscillator failure and avoid a malfunction behavior when entering stop mode.*

### Exiting Stop mode

The Stop mode is exited according to [Section : Exiting low-power mode](#).

Refer to [Table 19](#) for more details on how to exit Stop mode.

When exiting Stop mode by issuing an interrupt or a wakeup event, the HSI RC oscillator is selected as system clock.

When the voltage regulator operates in low-power mode, an additional startup delay is incurred when waking up from Stop mode. By keeping the internal regulator ON during Stop mode, the consumption is higher although the startup time is reduced.

**Table 19. Stop mode entry and exit**

Stop mode	Description
Mode entry	WFI (Wait for Interrupt) or WFE (Wait for Event) while: <ul style="list-style-type: none"> <li>– SLEEPDEEP bit is set in Cortex<sup>®</sup>-M4 with FPU System Control register</li> <li>– PDDS bit is cleared in Power Control register (PWR_CR)</li> <li>– Select the voltage regulator mode by configuring LPDS bit in PWR_CR.</li> </ul>
	On Return from ISR: <ul style="list-style-type: none"> <li>– SLEEPDEEP bit is set in Cortex<sup>®</sup>-M4 with FPU System Control register</li> <li>– SLEEPONEXIT = 1</li> <li>– PDDS bit is cleared in Power Control register (PWR_CR)</li> </ul>
	<i>Note: To enter Stop mode, all EXTI Line pending bits (in <a href="#">Pending register (EXTI_PR)</a>), all peripheral interrupts pending bits, the RTC Alarm (Alarm A and Alarm B), RTC wakeup, RTC tamper, and RTC time stamp flags, must be reset. Otherwise, the Stop mode entry procedure is ignored and program execution continues.</i>

Table 19. Stop mode entry and exit (continued)

Stop mode	Description
Mode exit	<p>If WFI or Return from ISR was used for entry: Any EXTI lines configured in Interrupt mode (the corresponding EXTI Interrupt vector must be enabled in the NVIC). The interrupt source can be external interrupts or peripherals with wakeup capability. Refer to <a href="#">Table 38: Vector table for STM32F401xB/CSTM32F401xD/E</a>.</p> <p>If WFE was used for entry and SEVONPEND = 0 Any EXTI lines configured in event mode. Refer to <a href="#">Section 10.2.3: Wakeup event management on page 205</a>.</p> <p>If WFE was used for entry and SEVONPEND = 1:  <ul style="list-style-type: none"> <li>– Any EXTI lines configured in Interrupt mode (even if the corresponding EXTI Interrupt vector is disabled in the NVIC). The interrupt source can be an external interrupt or a peripheral with wakeup capability. Refer to <a href="#">Table 38: Vector table for STM32F401xB/CSTM32F401xD/E</a>.</li> <li>– Wakeup event: refer to <a href="#">Section 10.2.3: Wakeup event management on page 205</a>.</li> </ul> </p>
Wakeup latency	<a href="#">Table 18: Stop operating modes</a>

### 5.3.5 Standby mode

The Standby mode allows to achieve the lowest power consumption. It is based on the Cortex<sup>®</sup>-M4 with FPU deepsleep mode, with the voltage regulator disabled. The 1.2 V domain is consequently powered off. The PLLs, the HSI oscillator and the HSE oscillator are also switched off. SRAM and register contents are lost except for registers in the backup domain (RTC registers and RTC backup register), and Standby circuitry (see [Figure 7](#)).

#### Entering Standby mode

The Standby mode is entered according to [Section : Entering low-power mode](#), when the SLEEPDEEP bit in the Cortex<sup>®</sup>-M4 with FPU System Control register is set.

Refer to [Table 20](#) for more details on how to enter Standby mode.

In Standby mode, the following features can be selected by programming individual control bits:

- Independent watchdog (IWDG): the IWDG is started by writing to its Key register or by hardware option. Once started it cannot be stopped except by a reset. See [Section 15.3](#) in [Section 15: Independent watchdog \(IWDG\)](#).
- Real-time clock (RTC): this is configured by the RTCEN bit in the backup domain control register (RCC\_BDCR)
- Internal RC oscillator (LSI RC): this is configured by the LSION bit in the Control/status register (RCC\_CSR).
- External 32.768 kHz oscillator (LSE OSC): this is configured by the LSEON bit in the backup domain control register (RCC\_BDCR)

#### Exiting Standby mode

The Standby mode is exited according to [Section : Exiting low-power mode](#). The SBF status flag in PWR\_CR (see [Section 5.4.2: PWR power control/status register \(PWR\\_CSR\)](#)) indicates that the MCU was in Standby mode. All registers are reset after wakeup from Standby except for PWR\_CR.

Refer to [Table 20](#) for more details on how to exit Standby mode.

**Table 20. Standby mode entry and exit**

Standby mode	Description
Mode entry	WFI (Wait for Interrupt) or WFE (Wait for Event) while: <ul style="list-style-type: none"> <li>– SLEEPDEEP is set in Cortex<sup>®</sup>-M4 with FPU System Control register</li> <li>– PDDS bit is set in Power Control register (PWR_CR)</li> <li>– CWUF bit is cleared in Power Control register (PWR_CR)</li> <li>– the RTC flag corresponding to the chosen wakeup source (RTC Alarm A, RTC Alarm B, RTC wakeup, Tamper or Timestamp flags) is cleared</li> </ul>
	On return from ISR while: <ul style="list-style-type: none"> <li>– SLEEPDEEP bit is set in Cortex<sup>®</sup>-M4 with FPU System Control register and</li> <li>– SLEEPONEXIT = 1 and</li> <li>– PDDS bit is set in Power Control register (PWR_CR) and</li> <li>– WUF bit is cleared in Power Control/Status register (PWR_SR)</li> </ul>
Mode exit	WKUP pin rising edge, RTC alarm (Alarm A and Alarm B), RTC wakeup, tamper event, time stamp event, external reset in NRST pin, IWDG reset.
Wakeup latency	Reset phase.

**I/O states in Standby mode**

In Standby mode, all I/O pins are high impedance except for:

- Reset pad (still available)
- RTC\_AF1 pin (PC13) if configured for tamper, time stamp, RTC Alarm out, or RTC clock calibration out
- WKUP pin (PA0), if enabled

**Debug mode**

By default, the debug connection is lost if the application puts the MCU in Stop or Standby mode while the debug features are used. This is due to the fact that the Cortex<sup>®</sup>-M4 with FPU core is no longer clocked.

However, by setting some configuration bits in the DBGMCU\_CR register, the software can be debugged even when using the low-power modes extensively. For more details, refer to [Section 23.16.1: Debug support for low-power modes](#).

**5.3.6 Programming the RTC alternate functions to wake up the device from the Stop and Standby modes**

The MCU can be woken up from a low-power mode by an RTC alternate function.

The RTC alternate functions are the RTC alarms (Alarm A and Alarm B), RTC wakeup, RTC tamper event detection and RTC time stamp event detection.

These RTC alternate functions can wake up the system from the Stop and Standby low-power modes.

The system can also wake up from low-power modes without depending on an external interrupt (Auto-wakeup mode), by using the RTC alarm or the RTC wakeup events.



The RTC provides a programmable time base for waking up from the Stop or Standby mode at regular intervals.

For this purpose, two of the three alternate RTC clock sources can be selected by programming the RTCSEL[1:0] bits in the [Section 6.3.17: RCC Backup domain control register \(RCC\\_BDCR\)](#):

- Low-power 32.768 kHz external crystal oscillator (LSE OSC)  
This clock source provides a precise time base with a very low-power consumption (additional consumption of less than 1  $\mu$ A under typical conditions)
- Low-power internal RC oscillator (LSI RC)  
This clock source has the advantage of saving the cost of the 32.768 kHz crystal. This internal RC oscillator is designed to use minimum power.

### RTC alternate functions to wake up the device from the Stop mode

- To wake up the device from the Stop mode with an RTC alarm event, it is necessary to:
  - a) Configure the EXTI Line 17 to be sensitive to rising edges (Interrupt or Event modes)
  - b) Enable the RTC Alarm Interrupt in the RTC\_CR register
  - c) Configure the RTC to generate the RTC alarm
- To wake up the device from the Stop mode with an RTC tamper or time stamp event, it is necessary to:
  - a) Configure the EXTI Line 21 to be sensitive to rising edges (Interrupt or Event modes)
  - b) Enable the RTC time stamp Interrupt in the RTC\_CR register or the RTC tamper interrupt in the RTC\_TAFPCR register
  - c) Configure the RTC to detect the tamper or time stamp event
- To wake up the device from the Stop mode with an RTC wakeup event, it is necessary to:
  - a) Configure the EXTI Line 22 to be sensitive to rising edges (Interrupt or Event modes)
  - b) Enable the RTC wakeup interrupt in the RTC\_CR register
  - c) Configure the RTC to generate the RTC Wakeup event

### RTC alternate functions to wake up the device from the Standby mode

- To wake up the device from the Standby mode with an RTC alarm event, it is necessary to:
  - a) Enable the RTC alarm interrupt in the RTC\_CR register
  - b) Configure the RTC to generate the RTC alarm
- To wake up the device from the Standby mode with an RTC tamper or time stamp event, it is necessary to:
  - a) Enable the RTC time stamp interrupt in the RTC\_CR register or the RTC tamper interrupt in the RTC\_TAFPCR register
  - b) Configure the RTC to detect the tamper or time stamp event
- To wake up the device from the Standby mode with an RTC wakeup event, it is necessary to:
  - a) Enable the RTC wakeup interrupt in the RTC\_CR register

- b) Configure the RTC to generate the RTC wakeup event

### Safe RTC alternate function wakeup flag clearing sequence

If the selected RTC alternate function is set before the PWR wakeup flag (WUTF) is cleared, it will not be detected on the next event as detection is made once on the rising edge.

To avoid bouncing on the pins onto which the RTC alternate functions are mapped, and exit correctly from the Stop and Standby modes, it is recommended to follow the sequence below before entering the Standby mode:

- When using RTC alarm to wake up the device from the low-power modes:
  - a) Disable the RTC alarm interrupt (ALRAIE or ALRBIE bits in the RTC\_CR register)
  - b) Clear the RTC alarm (ALRAF/ALRBF) flag
  - c) Clear the PWR Wakeup (WUF) flag
  - d) Enable the RTC alarm interrupt
  - e) Re-enter the low-power mode
- When using RTC wakeup to wake up the device from the low-power modes:
  - a) Disable the RTC Wakeup interrupt (WUTIE bit in the RTC\_CR register)
  - b) Clear the RTC Wakeup (WUTF) flag
  - c) Clear the PWR Wakeup (WUF) flag
  - d) Enable the RTC Wakeup interrupt
  - e) Re-enter the low-power mode
- When using RTC tamper to wake up the device from the low-power modes:
  - a) Disable the RTC tamper interrupt (TAMPIE bit in the RTC\_TAFCR register)
  - b) Clear the Tamper (TAMP1F/TSF) flag
  - c) Clear the PWR Wakeup (WUF) flag
  - d) Enable the RTC tamper interrupt
  - e) Re-enter the low-power mode
- When using RTC time stamp to wake up the device from the low-power modes:
  - a) Disable the RTC time stamp interrupt (TSIE bit in RTC\_CR)
  - b) Clear the RTC time stamp (TSF) flag
  - c) Clear the PWR Wakeup (WUF) flag
  - d) Enable the RTC TimeStamp interrupt
  - e) Re-enter the low-power mode

## 5.4 Power control registers

### 5.4.1 PWR power control register (PWR\_CR)

Address offset: 0x00

Reset value: 0x0000 8000 (reset by wakeup from Standby mode)

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved															
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
VOS		ADCDC1	Res	MRLV DS	LPLV DS	FPDS	DBP	PLS[2:0]			PVDE	CSBF	CWUF	PDDS	LPDS
r/w	r/w	r/w		r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	w	w	r/w	r/w

Bits 31:16 Reserved, must be kept at reset value.

Bits 15:14 **VOS[1:0]**: Regulator voltage scaling output selection

These bits control the main internal voltage regulator output voltage to achieve a trade-off between performance and power consumption when the device does not operate at the maximum frequency (refer to the corresponding datasheet for more details).

These bits can be modified only when the PLL is OFF. The new value programmed is active only when the PLL is ON. When the PLL is OFF, the voltage regulator is set to scale 3 independently of the VOS register content.

00: Reserved (Scale 3 mode selected)

01: Scale 3 mode

10: Scale 2 mode

11: Reserved (Scale 2 mode selected)

Bit 13 **ADCDC1**:

0: No effect.

1: Refer to AN4073 for details on how to use this bit.

*Note: This bit can only be set when operating at supply voltage range 2.7 to 3.6V and when the Prefetch is OFF.*

Bit 12 Reserved, must be kept at reset value.

Bit 11 **MRLVDS**: Main regulator Low Voltage in Deep Sleep

0: Main regulator in Voltage scale 3 when the device is in Stop mode.

1: Main regulator in Low Voltage and Flash memory in Deep Sleep mode when the device is in Stop mode.

Bit 10 **LPLVDS**: Low-power regulator Low Voltage in Deep Sleep

0: Low-power regulator on if LPDS bit is set when the device is in Stop mode.

1: Low-power regulator in Low Voltage and Flash memory in Deep Sleep mode if LPDS bit is set when device is in Stop mode.

Bit 9 **FPDS**: Flash power-down in Stop mode

When set, the Flash memory enters power-down mode when the device enters Stop mode. This allows to achieve a lower consumption in stop mode but a longer restart time.

0: Flash memory not in power-down when the device is in Stop mode

1: Flash memory in power-down when the device is in Stop mode

**Bit 8 DBP:** Disable backup domain write protection

In reset state, the RCC\_BDCR register, the RTC registers (including the backup registers), and the BRE bit of the PWR\_CSR register, are protected against parasitic write access. This bit must be set to enable write access to these registers.

0: Access to RTC and RTC Backup registers.

1: Access to RTC and RTC Backup registers.

**Bits 7:5 PLS[2:0]:** PVD level selection

These bits are written by software to select the voltage threshold detected by the Power Voltage Detector

000: 2.2 V

001: 2.3 V

010: 2.4 V

011: 2.5 V

100: 2.6 V

101: 2.7 V

110: 2.8 V

111: 2.9 V

*Note: Refer to the electrical characteristics of the datasheet for more details.*

**Bit 4 PVDE:** Power voltage detector enable

This bit is set and cleared by software.

0: PVD disabled

1: PVD enabled

**Bit 3 CSBF:** Clear standby flag

This bit is always read as 0.

0: No effect.

1: Clear the SBF Standby Flag (write).

**Bit 2 CWUF:** Clear wakeup flag

This bit is always read as 0.

0: No effect.

1: Clear the WUF Wakeup Flag after 2 System clock cycles.

**Bit 1 PDDS:** Power-down deepsleep

This bit is set and cleared by software. It works together with the LPDS bit.

0: Enter Stop mode when the CPU enters deepsleep. The regulator status depends on the LPDS bit.

1: Enter Standby mode when the CPU enters deepsleep.

**Bit 0 LPDS:** Low-power deepsleep

This bit is set and cleared by software. It works together with the PDDS bit.

0: Voltage regulator on during Stop mode.

1: Low-power Voltage regulator on during Stop mode.

### 5.4.2 PWR power control/status register (PWR\_CSR)

Address offset: 0x04

Reset value: 0x0000 0000 (not reset by wakeup from Standby mode)

Additional APB cycles are needed to read this register versus a standard APB read.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	
Reserved																
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
Res	VOS RDY	Reserved					BRE	EWUP	Reserved				BRR	PVDO	SBF	WUF
	r						rw	rw					r	r	r	r

Bits 31:15 Reserved, must be kept at reset value.

Bit 14 **VOSRDY**: Regulator voltage scaling output selection ready bit

- 0: Not ready
- 1: Ready

Bits 13:10 Reserved, must be kept at reset value.

Bit 9 **BRE**: Backup regulator enable

When set, the Backup regulator (used to maintain the backup domain content) is enabled. If BRE is reset, the backup regulator is switched off. Once set, the application must wait that the Backup Regulator Ready flag (BRR) is set to indicate that the data written into the backup registers will be maintained in the Standby and V<sub>BAT</sub> modes.

- 0: Backup regulator disabled
- 1: Backup regulator enabled

*Note: This bit is not reset when the device wakes up from Standby mode, by a system reset, or by a power reset.*

Bit 8 **EWUP**: Enable WKUP pin

This bit is set and cleared by software.

- 0: WKUP pin is used for general purpose I/O. An event on the WKUP pin does not wakeup the device from Standby mode.
- 1: WKUP pin is used for wakeup from Standby mode and forced in input pull down configuration (rising edge on WKUP pin wakes-up the system from Standby mode).

*Note: This bit is reset by a system reset.*

Bits 7:4 Reserved, must be kept at reset value.

Bit 3 **BRR**: Backup regulator ready

Set by hardware to indicate that the Backup Regulator is ready.

- 0: Backup Regulator not ready
- 1: Backup Regulator ready

*Note: This bit is not reset when the device wakes up from Standby mode or by a system reset or power reset.*

Bit 2 **PVDO**: PVD output

This bit is set and cleared by hardware. It is valid only if PVD is enabled by the PVDE bit.

- 0: V<sub>DD</sub> is higher than the PVD threshold selected with the PLS[2:0] bits.
- 1: V<sub>DD</sub> is lower than the PVD threshold selected with the PLS[2:0] bits.

*Note: The PVD is stopped by Standby mode. For this reason, this bit is equal to 0 after Standby or reset until the PVDE bit is set.*

Bit 1 **SBF**: Standby flag

This bit is set by hardware and cleared only by a POR/PDR (power-on reset/power-down reset) or by setting the CSBF bit in the PWR\_CR register.

- 0: Device has not been in Standby mode
- 1: Device has been in Standby mode

Bit 0 **WUF**: Wakeup flag

This bit is set by hardware and cleared either by a system reset or by setting the CWUF bit in the PWR\_CR register.

- 0: No wakeup event occurred
- 1: A wakeup event was received from the WKUP pin or from the RTC alarm (Alarm A or Alarm B), RTC Tamper event, RTC TimeStamp event or RTC Wakeup).

*Note: An additional wakeup event is detected if the WKUP pin is enabled (by setting the EWUP bit) when the WKUP pin level is already high.*

### 5.5 PWR register map

The following table summarizes the PWR registers.

**Table 21. PWR - register map and reset values**

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0												
0x000	<b>PWR_CR</b>	Reserved																	VOS[1:0]	ADCDC1	Reserved	MRLVDS	LPLVDS	FPDS	DBP	PLS[2:0]			PVDE	CSBF	CWUF	PDDS	LPDS												
	Reset value																		1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x004	<b>PWR_CSR</b>	Reserved																	VOSRDY	Reserved					BRE	EWUP	Reserved			BRR	PVDO	SBF	WUF												
	Reset value																		0						0	0				0	0	0	0												

Refer to [Table 1 on page 38](#) for the register boundary addresses.

## 6 Reset and clock control (RCC) for STM32F401xB/C and STM32F401xD/E

### 6.1 Reset

There are three types of reset, defined as system Reset, power Reset and backup domain Reset.

#### 6.1.1 System reset

A system reset sets all registers to their reset values except the reset flags in the clock controller CSR register and the registers in the Backup domain.

A system reset is generated when one of the following events occurs:

1. A low level on the NRST pin (external reset)
2. Window watchdog end of count condition (WWDG reset)
3. Independent watchdog end of count condition (IWDG reset)
4. A software reset (SW reset) (see [Software reset](#))
5. Low-power management reset (see [Low-power management reset](#))

#### Software reset

The reset source can be identified by checking the reset flags in the [RCC clock control & status register \(RCC\\_CSR\)](#).

The SYSRESETREQ bit in Cortex<sup>®</sup>-M4 with FPU Application Interrupt and Reset Control Register must be set to force a software reset on the device. Refer to the Cortex<sup>®</sup>-M4 with FPU technical reference manual for more details.

### Low-power management reset

There are two ways of generating a low-power management reset:

1. Reset generated when entering the Standby mode:  
 This type of reset is enabled by resetting the nRST\_STDBY bit in the user option bytes. In this case, whenever a Standby mode entry sequence is successfully executed, the device is reset instead of entering the Standby mode.
2. Reset when entering the Stop mode:  
 This type of reset is enabled by resetting the nRST\_STOP bit in the user option bytes. In this case, whenever a Stop mode entry sequence is successfully executed, the device is reset instead of entering the Stop mode.

For further information on the user option bytes, refer to the STM32F401xB/C and STM32F401xD/E Flash programming manual available from your ST sales office.

### 6.1.2 Power reset

A power reset is generated when one of the following events occurs:

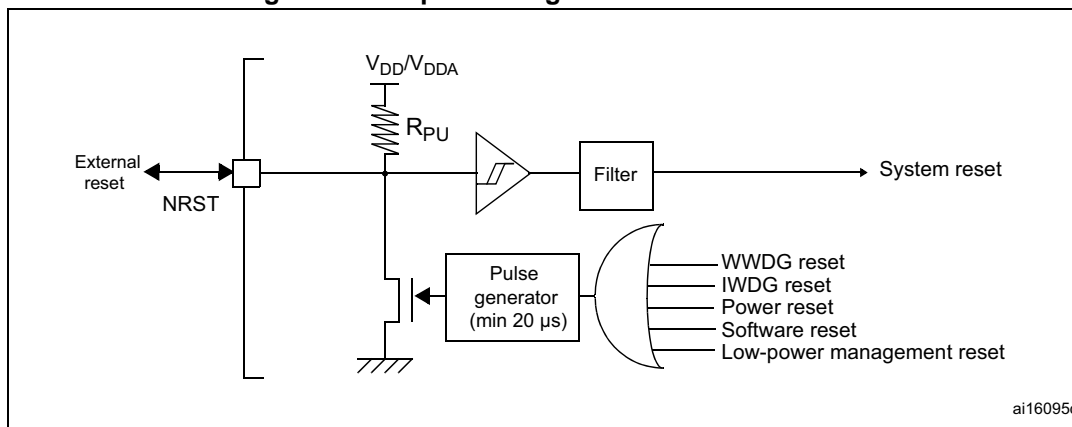
1. Power-on/power-down reset (POR/PDR reset) or brownout (BOR) reset
2. When exiting the Standby mode

A power reset sets all registers to their reset values except the Backup domain.

These sources act on the NRST pin and it is always kept low during the delay phase. The RESET service routine vector is fixed at address 0x0000\_0004 in the memory map.

The system reset signal provided to the device is output on the NRST pin. The pulse generator guarantees a minimum reset pulse duration of 20  $\mu$ s for each internal reset source. In case of an external reset, the reset pulse is generated while the NRST pin is asserted low.

Figure 11. Simplified diagram of the reset circuit





### 6.1.3 Backup domain reset

The backup domain reset sets all RTC registers and the RCC\_BDCR register to their reset values.

A backup domain reset is generated when one of the following events occurs:

1. Software reset, triggered by setting the BDRST bit in the *RCC Backup domain control register (RCC\_BDCR)*.
2.  $V_{DD}$  or  $V_{BAT}$  power on, if both supplies have previously been powered off.

## 6.2 Clocks

Three different clock sources can be used to drive the system clock (SYSCLK):

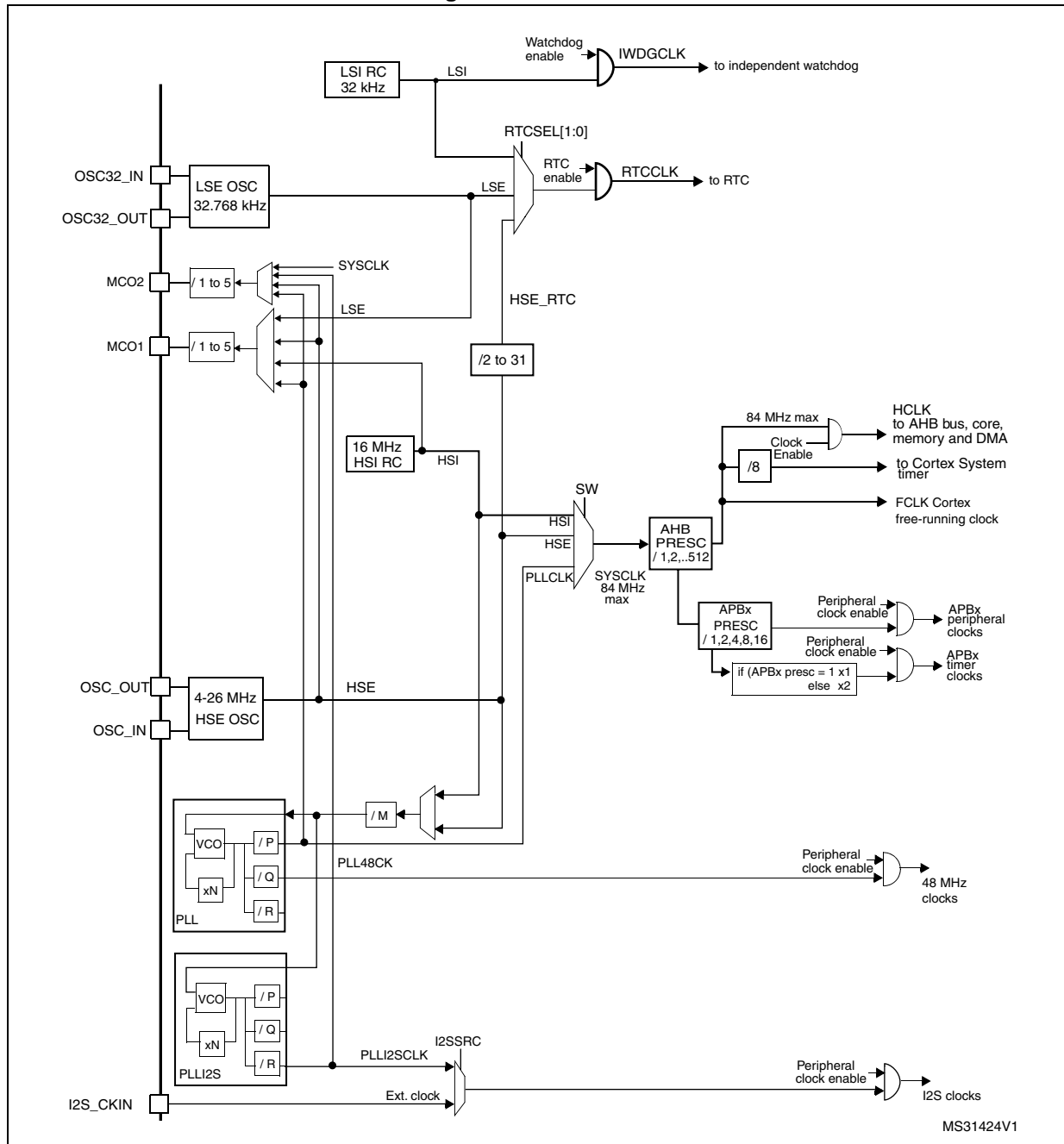
- HSI oscillator clock
- HSE oscillator clock
- Main PLL (PLL) clock

The devices have the two following secondary clock sources:

- 32 kHz low-speed internal RC (LSI RC) which drives the independent watchdog and, optionally, the RTC used for Auto-wakeup from the Stop/Standby mode.
- 32.768 kHz low-speed external crystal (LSE crystal) which optionally drives the RTC clock (RTCCLK)

Each clock source can be switched on or off independently when it is not used, to optimize power consumption.

Figure 12. Clock tree



1. For full details about the internal and external clock source characteristics, refer to the Electrical characteristics section in the device datasheet.

The clock controller provides a high degree of flexibility to the application in the choice of the external crystal or the oscillator to run the core and peripherals at the highest frequency and, guarantee the appropriate frequency for peripherals that need a specific clock like USB OTG FS, I2S and SDIO.

Several prescalers are used to configure the AHB frequency, the high-speed APB (APB2) and the low-speed APB (APB1) domains. The maximum frequency of the AHB domain is 84 MHz. The maximum allowed frequency of the high-speed APB2 domain is 84 MHz. The maximum allowed frequency of the low-speed APB1 domain is 42 MHz

All peripheral clocks are derived from the system clock (SYSCLK) except for:

- The USB OTG FS clock (48 MHz) and the SDIO clock ( $\leq 48$  MHz) which are coming from a specific output of PLL (PLL48CLK)

- The I2S clock

To achieve high-quality audio performance, the I2S clock can be derived either from a specific PLL (PLLI2S) or from an external clock mapped on the I2S\_CKIN pin. For more information about I2S clock frequency and precision, refer to [Section 20.4.4: Clock generator](#).

The RCC feeds the external clock of the Cortex System Timer (SysTick) with the AHB clock (HCLK) divided by 8. The SysTick can work either with this clock or with the Cortex clock (HCLK), configurable in the SysTick control and status register.

The timer clock frequencies for STM32F401xB/C and STM32F401xD/E are automatically set by hardware. There are two cases:

1. If the APB prescaler is 1, the timer clock frequencies are set to the same frequency as that of the APB domain to which the timers are connected.
2. Otherwise, they are set to twice ( $\times 2$ ) the frequency of the APB domain to which the timers are connected.

The timer clock frequencies are automatically set by hardware. There are two cases depending on the value of TIMPRE bit in RCC\_DCKCFGR register:

- If TIMPRE bit is reset:  
If the APB prescaler is configured to a division factor of 1, the timer clock frequencies (TIMxCLK) are set to HCLK. Otherwise, the timer clock frequencies are twice the frequency of the APB domain to which the timers are connected:  $TIMxCLK = 2 \times PCLKx$ .
- If TIMPRE bit is set:  
If the APB prescaler is configured to a division factor of 1 or 2, the timer clock frequencies (TIMxCLK) are set to HCLK. Otherwise, the timer clock frequencies is four times the frequency of the APB domain to which the timers are connected:  $TIMxCLK = 4 \times PCLKx$ .

FCLK acts as Cortex<sup>®</sup>-M4 with FPU free-running clock. For more details, refer to the Cortex<sup>®</sup>-M4 with FPU technical reference manual.

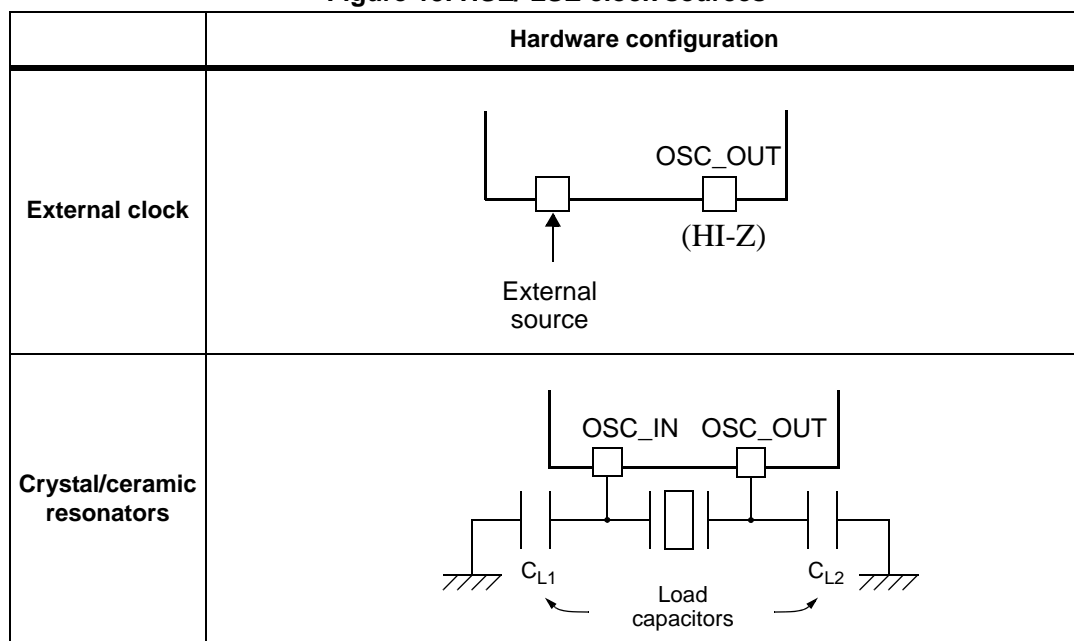
### 6.2.1 HSE clock

The high speed external clock signal (HSE) can be generated from two possible clock sources:

- HSE external crystal/ceramic resonator
- HSE external user clock

The resonator and the load capacitors have to be placed as close as possible to the oscillator pins in order to minimize output distortion and startup stabilization time. The loading capacitance values must be adjusted according to the selected oscillator.

**Figure 13. HSE/ LSE clock sources**



#### External source (HSE bypass)

In this mode, an external clock source must be provided. You select this mode by setting the HSEBYP and HSEON bits in the *RCC clock control register (RCC\_CR)*. The external clock signal (square, sinus or triangle) with ~50% duty cycle has to drive the OSC\_IN pin while the OSC\_OUT pin should be left HI-Z. See *Figure 13*.

#### External crystal/ceramic resonator (HSE crystal)

The HSE has the advantage of producing a very accurate rate on the main clock.

The associated hardware configuration is shown in *Figure 13*. Refer to the electrical characteristics section of the *datasheet* for more details.

The HSERDY flag in the *RCC clock control register (RCC\_CR)* indicates if the high-speed external oscillator is stable or not. At startup, the clock is not released until this bit is set by hardware. An interrupt can be generated if enabled in the *RCC clock interrupt register (RCC\_CIR)*.

The HSE Crystal can be switched on and off using the HSEON bit in the *RCC clock control register (RCC\_CR)*.

## 6.2.2 HSI clock

The HSI clock signal is generated from an internal 16 MHz RC oscillator and can be used directly as a system clock, or used as PLL input.

The HSI RC oscillator has the advantage of providing a clock source at low cost (no external components). It also has a faster startup time than the HSE crystal oscillator however, even with calibration the frequency is less accurate than an external crystal oscillator or ceramic resonator.

### Calibration

RC oscillator frequencies can vary from one chip to another due to manufacturing process variations, this is why each device is factory calibrated by ST for 1% accuracy at  $T_A = 25\text{ }^\circ\text{C}$ .

After reset, the factory calibration value is loaded in the HSICAL[7:0] bits in the [RCC clock control register \(RCC\\_CR\)](#).

If the application is subject to voltage or temperature variations this may affect the RC oscillator speed. You can trim the HSI frequency in the application using the HSITRIM[4:0] bits in the [RCC clock control register \(RCC\\_CR\)](#).

The HSIRDY flag in the [RCC clock control register \(RCC\\_CR\)](#) indicates if the HSI RC is stable or not. At startup, the HSI RC output clock is not released until this bit is set by hardware.

The HSI RC can be switched on and off using the HSION bit in the [RCC clock control register \(RCC\\_CR\)](#).

The HSI signal can also be used as a backup source (Auxiliary clock) if the HSE crystal oscillator fails. Refer to [Section 6.2.7: Clock security system \(CSS\) on page 98](#).

## 6.2.3 PLL configuration

The STM32F401xB/C and STM32F401xD/E devices feature two PLLs:

- A main PLL (PLL) clocked by the HSE or HSI oscillator and featuring two different output clocks:
  - The first output is used to generate the high speed system clock (up to 84 MHz)
  - The second output is used to generate the clock for the USB OTG FS (48 MHz), the random analog generator ( $\leq 48\text{ MHz}$ ) and the SDIO ( $\leq 48\text{ MHz}$ ).
- A dedicated PLL (PLLI2S) used to generate an accurate clock to achieve high-quality audio performance on the I2S interface.

Since the main-PLL configuration parameters cannot be changed once PLL is enabled, it is recommended to configure PLL before enabling it (selection of the HSI or HSE oscillator as PLL clock source, and configuration of division factors M, P, Q and multiplication factor N).

The PLLI2S uses the same input clock as the main PLL (PLLM[5:0] and PLLSRC bits are common to both PLLs). However, the PLLI2S has dedicated enable/disable and division factors configuration bits. Refer to [Section 6.3.1: RCC clock control register \(RCC\\_CR\)](#), [Section 6.3.2: RCC PLL configuration register \(RCC\\_PLLCFGR\)](#) and [Section 6.3.20: RCC PLLI2S configuration register \(RCC\\_PLLI2SCFGR\)](#). Once the PLLI2S is enabled, the configuration parameters cannot be changed.

The two PLLs are disabled by hardware when entering Stop and Standby modes, or when an HSE failure occurs when HSE or PLL (clocked by HSE) are used as system clock. [RCC](#)

[PLL configuration register \(RCC\\_PLLCFGR\)](#) and [RCC clock configuration register \(RCC\\_CFGR\)](#) can be used to configure PLL and PLLI2S, respectively.

#### 6.2.4 LSE clock

The LSE clock is generated using a 32.768kHz low speed external crystal or ceramic resonator. It has the advantage providing a low-power but highly accurate clock source to the real-time clock peripheral (RTC) for clock/calendar or other timing functions.

The LSE oscillator is switched on and off using the LSEON bit in [RCC Backup domain control register \(RCC\\_BDCR\)](#).

The LSERDY flag in the [RCC Backup domain control register \(RCC\\_BDCR\)](#) indicates if the LSE crystal is stable or not. At startup, the LSE crystal output clock signal is not released until this bit is set by hardware. An interrupt can be generated if enabled in the [RCC clock interrupt register \(RCC\\_CIR\)](#).

##### External source (LSE bypass)

In this mode, an external clock source must be provided. It must have a frequency up to 1 MHz. You select this mode by setting the LSEBYP and LSEON bits in the [RCC Backup domain control register \(RCC\\_BDCR\)](#). The external clock signal (square, sinus or triangle) with ~50% duty cycle has to drive the OSC32\_IN pin while the OSC32\_OUT pin should be left HI-Z. See [Figure 13](#).

#### 6.2.5 LSI clock

The LSI RC acts as an low-power clock source that can be kept running in Stop and Standby mode for the independent watchdog (IWDG) and Auto-wakeup unit (AWU). The clock frequency is around 32 kHz. For more details, refer to the electrical characteristics section of the datasheets.

The LSI RC can be switched on and off using the LSION bit in the [RCC clock control & status register \(RCC\\_CSR\)](#).

The LSIRDY flag in the [RCC clock control & status register \(RCC\\_CSR\)](#) indicates if the low-speed internal oscillator is stable or not. At startup, the clock is not released until this bit is set by hardware. An interrupt can be generated if enabled in the [RCC clock interrupt register \(RCC\\_CIR\)](#).

#### 6.2.6 System clock (SYSCLK) selection

After a system reset, the HSI oscillator is selected as the system clock. When a clock source is used directly or through PLL as the system clock, it is not possible to stop it.

A switch from one clock source to another occurs only if the target clock source is ready (clock stable after startup delay or PLL locked). If a clock source that is not yet ready is selected, the switch occurs when the clock source is ready. Status bits in the [RCC clock control register \(RCC\\_CR\)](#) indicate which clock(s) is (are) ready and which clock is currently used as the system clock.

## 6.2.7 Clock security system (CSS)

The clock security system can be activated by software. In this case, the clock detector is enabled after the HSE oscillator startup delay, and disabled when this oscillator is stopped.

If a failure is detected on the HSE clock, this oscillator is automatically disabled, a clock failure event is sent to the break inputs of advanced-control timer TIM1, and an interrupt is generated to inform the software about the failure (clock security system interrupt CSSI), allowing the MCU to perform rescue operations. The CSSI is linked to the Cortex<sup>®</sup>-M4 with FPU NMI (non-maskable interrupt) exception vector.

*Note:* When the CSS is enabled, if the HSE clock happens to fail, the CSS generates an interrupt, which causes the automatic generation of an NMI. The NMI is executed indefinitely unless the CSS interrupt pending bit is cleared. As a consequence, the application has to clear the CSS interrupt in the NMI ISR by setting the CSSC bit in the Clock interrupt register (RCC\_CIR).

If the HSE oscillator is used directly or indirectly as the system clock (indirectly meaning that it is directly used as PLL input clock, and that PLL clock is the system clock) and a failure is detected, then the system clock switches to the HSI oscillator and the HSE oscillator is disabled.

If the HSE oscillator clock was the clock source of PLL used as the system clock when the failure occurred, PLL is also disabled. In this case, if the PLLI2S was enabled, it is also disabled when the HSE fails.

## 6.2.8 RTC/AWU clock

Once the RTCCLK clock source has been selected, the only possible way of modifying the selection is to reset the power domain.

The RTCCLK clock source can be either the HSE 1 MHz (HSE divided by a programmable prescaler), the LSE or the LSI clock. This is selected by programming the RTCSEL[1:0] bits in the *RCC Backup domain control register (RCC\_BDCR)* and the RTCPRE[4:0] bits in *RCC clock configuration register (RCC\_CFGR)*. This selection cannot be modified without resetting the Backup domain.

If the LSE is selected as the RTC clock, the RTC will work normally if the backup or the system supply disappears. If the LSI is selected as the AWU clock, the AWU state is not guaranteed if the system supply disappears. If the HSE oscillator divided by a value between 2 and 31 is used as the RTC clock, the RTC state is not guaranteed if the backup or the system supply disappears.

The LSE clock is in the Backup domain, whereas the HSE and LSI clocks are not. As a consequence:

- If LSE is selected as the RTC clock:
  - The RTC continues to work even if the  $V_{DD}$  supply is switched off, provided the  $V_{BAT}$  supply is maintained.
- If LSI is selected as the Auto-wakeup unit (AWU) clock:
  - The AWU state is not guaranteed if the  $V_{DD}$  supply is powered off. Refer to [Section 6.2.5: LSI clock on page 97](#) for more details on LSI calibration.
- If the HSE clock is used as the RTC clock:
  - The RTC state is not guaranteed if the  $V_{DD}$  supply is powered off or if the internal voltage regulator is powered off (removing power from the 1.2 V domain).

*Note:* To read the RTC calendar register when the APB1 clock frequency is less than seven times the RTC clock frequency ( $f_{APB1} < 7 \times f_{RTCLCK}$ ), the software must read the calendar time and date registers twice. The data are correct if the second read access to RTC\_TR gives the same result than the first one. Otherwise a third read access must be performed.

## 6.2.9 Watchdog clock

If the independent watchdog (IWDG) is started by either hardware option or software access, the LSI oscillator is forced ON and cannot be disabled. After the LSI oscillator temporization, the clock is provided to the IWDG.

## 6.2.10 Clock-out capability

Two microcontroller clock output (MCO) pins are available:

- MCO1

You can output four different clock sources onto the MCO1 pin (PA8) using the configurable prescaler (from 1 to 5):

- HSI clock
- LSE clock
- HSE clock
- PLL clock

The desired clock source is selected using the MCO1PRE[2:0] and MCO1[1:0] bits in the [RCC clock configuration register \(RCC\\_CFGR\)](#).

- MCO2

You can output four different clock sources onto the MCO2 pin (PC9) using the configurable prescaler (from 1 to 5):

- HSE clock
- PLL clock
- System clock (SYSCLK)
- PLLI2S clock

The desired clock source is selected using the MCO2PRE[2:0] and MCO2 bits in the [RCC clock configuration register \(RCC\\_CFGR\)](#).

For the different MCO pins, the corresponding GPIO port has to be programmed in alternate function mode.

The selected clock to output onto MCO must not exceed 100 MHz (the maximum I/O speed).

## 6.2.11 Internal/external clock measurement using TIM5/TIM11

It is possible to indirectly measure the frequencies of all on-board clock source generators by means of the input capture of TIM5 channel4 and TIM11 channel1 as shown in [Figure 14](#) and [Figure 15](#).

### Internal/external clock measurement using TIM5 channel4

TIM5 has an input multiplexer which allows choosing whether the input capture is triggered by the I/O or by an internal clock. This selection is performed through the TI4\_RMP [1:0] bits in the TIM5\_OR register.



The primary purpose of having the LSE connected to the channel4 input capture is to be able to precisely measure the HSI (this requires to have the HSI used as the system clock source). The number of HSI clock counts between consecutive edges of the LSE signal provides a measurement of the internal clock period. Taking advantage of the high precision of LSE crystals (typically a few tens of ppm) we can determine the internal clock frequency with the same resolution, and trim the source to compensate for manufacturing-process and/or temperature- and voltage-related frequency deviations.

The HSI oscillator has dedicated, user-accessible calibration bits for this purpose.

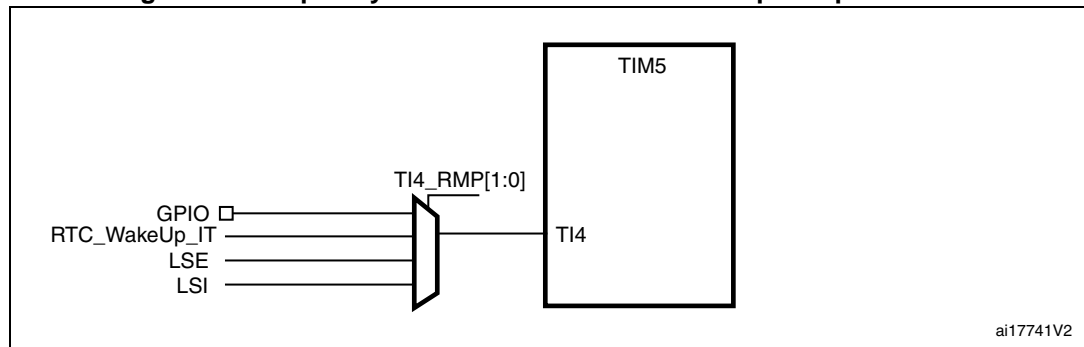
The basic concept consists in providing a relative measurement (e.g. HSI/LSE ratio): the precision is therefore tightly linked to the ratio between the two clock sources. The greater the ratio, the better the measurement.

It is also possible to measure the LSI frequency: this is useful for applications that do not have a crystal. The ultralow-power LSI oscillator has a large manufacturing process deviation: by measuring it versus the HSI clock source, it is possible to determine its frequency with the precision of the HSI. The measured value can be used to have more accurate RTC time base timeouts (when LSI is used as the RTC clock source) and/or an IWDG timeout with an acceptable accuracy.

Use the following procedure to measure the LSI frequency:

1. Enable the TIM5 timer and configure channel4 in Input capture mode.
2. Set the TI4\_RMP bits in the TIM5\_OR register to 0x01 to connect the LSI clock internally to TIM5 channel4 input capture for calibration purposes.
3. Measure the LSI clock frequency using the TIM5 capture/compare 4 event or interrupt.
4. Use the measured LSI frequency to update the prescaler of the RTC depending on the desired time base and/or to compute the IWDG timeout.

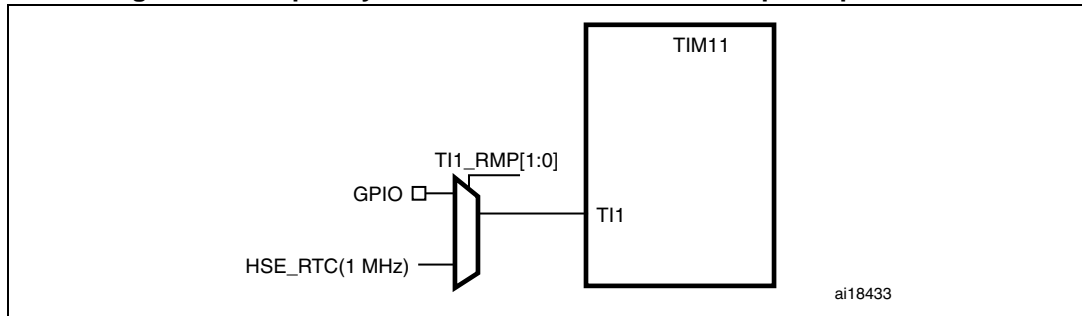
**Figure 14. Frequency measurement with TIM5 in Input capture mode**



**Internal/external clock measurement using TIM11 channel1**

TIM11 has an input multiplexer which allows choosing whether the input capture is triggered by the I/O or by an internal clock. This selection is performed through TI1\_RMP [1:0] bits in the TIM11\_OR register. The HSE\_RTC clock (HSE divided by a programmable prescaler) is connected to channel 1 input capture to have a rough indication of the external crystal frequency. This requires that the HSI is the system clock source. This can be useful for instance to ensure compliance with the IEC 60730/IEC 61335 standards which require to be able to determine harmonic or subharmonic frequencies (-50/+100% deviations).

**Figure 15. Frequency measurement with TIM11 in Input capture mode**



## 6.3 RCC registers

Refer to [Section 1.1: List of abbreviations for registers](#) for a list of abbreviations used in register descriptions.

### 6.3.1 RCC clock control register (RCC\_CR)

Address offset: 0x00

Reset value: 0x0000 XX81 where X is undefined.

Access: no wait state, word, half-word and byte access

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved				PLLI2S RDY	PLLI2S ON	PLLRDY	PLLON	Reserved				CSS ON	HSE BYP	HSE RDY	HSE ON
				r	rw	r	rw					rw	rw	r	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
HSICAL[7:0]								HSITRIM[4:0]					Res.	HSI RDY	HSION
r	r	r	r	r	r	r	r	rw	rw	rw	rw	rw		r	rw

Bits 31:28 Reserved, must be kept at reset value.

Bit 27 **PLLI2SRDY**: PLLI2S clock ready flag

Set by hardware to indicate that the PLLI2S is locked.

0: PLLI2S unlocked

1: PLLI2S locked

Bit 26 **PLLI2SON**: PLLI2S enable

Set and cleared by software to enable PLLI2S.

Cleared by hardware when entering Stop or Standby mode.

0: PLLI2S OFF

1: PLLI2S ON

Bit 25 **PLLRDY**: Main PLL (PLL) clock ready flag

Set by hardware to indicate that PLL is locked.

0: PLL unlocked

1: PLL locked

Bit 24 **PLLON**: Main PLL (PLL) enable

Set and cleared by software to enable PLL.

Cleared by hardware when entering Stop or Standby mode. This bit cannot be reset if PLL clock is used as the system clock.

0: PLL OFF

1: PLL ON

Bits 23:20 Reserved, must be kept at reset value.

Bit 19 **CSSON**: Clock security system enable

Set and cleared by software to enable the clock security system. When CSSON is set, the clock detector is enabled by hardware when the HSE oscillator is ready, and disabled by hardware if an oscillator failure is detected.

0: Clock security system OFF (Clock detector OFF)

1: Clock security system ON (Clock detector ON if HSE oscillator is stable, OFF if not)

Bit 18 **HSEBYP**: HSE clock bypass

Set and cleared by software to bypass the oscillator with an external clock. The external clock must be enabled with the HSEON bit, to be used by the device.

The HSEBYP bit can be written only if the HSE oscillator is disabled.

0: HSE oscillator not bypassed

1: HSE oscillator bypassed with an external clock

Bit 17 **HSERDY**: HSE clock ready flag

Set by hardware to indicate that the HSE oscillator is stable. After the HSEON bit is cleared, HSERDY goes low after 6 HSE oscillator clock cycles.

0: HSE oscillator not ready

1: HSE oscillator ready

Bit 16 **HSEON**: HSE clock enable

Set and cleared by software.

Cleared by hardware to stop the HSE oscillator when entering Stop or Standby mode. This bit cannot be reset if the HSE oscillator is used directly or indirectly as the system clock.

0: HSE oscillator OFF

1: HSE oscillator ON

Bits 15:8 **HSICAL[7:0]**: Internal high-speed clock calibration

These bits are initialized automatically at startup.

Bits 7:3 **HSITRIM[4:0]**: Internal high-speed clock trimming

These bits provide an additional user-programmable trimming value that is added to the HSICAL[7:0] bits. It can be programmed to adjust to variations in voltage and temperature that influence the frequency of the internal HSI RC.

Bit 2 Reserved, must be kept at reset value.

Bit 1 **HSIRDY**: Internal high-speed clock ready flag

Set by hardware to indicate that the HSI oscillator is stable. After the HSION bit is cleared, HSIRDY goes low after 6 HSI clock cycles.

0: HSI oscillator not ready

1: HSI oscillator ready

Bit 0 **HSION**: Internal high-speed clock enable

Set and cleared by software.

Set by hardware to force the HSI oscillator ON when leaving the Stop or Standby mode or in case of a failure of the HSE oscillator used directly or indirectly as the system clock. This bit cannot be cleared if the HSI is used directly or indirectly as the system clock.

0: HSI oscillator OFF

1: HSI oscillator ON

### 6.3.2 RCC PLL configuration register (RCC\_PLLCFGR)

Address offset: 0x04

Reset value: 0x2400 3010

Access: no wait state, word, half-word and byte access.

This register is used to configure the PLL clock outputs according to the formulas:

- $f_{(VCO\ clock)} = f_{(PLL\ clock\ input)} \times (PLLN / PLLM)$
- $f_{(PLL\ general\ clock\ output)} = f_{(VCO\ clock)} / PLLP$
- $f_{(USB\ OTG\ FS,\ SDIO,\ RNG\ clock\ output)} = f_{(VCO\ clock)} / PLLQ$

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved				PLLQ3	PLLQ2	PLLQ1	PLLQ0	Reserved	PLLSRC	Reserved				PLL1P1	PLL1P0
				rw	rw	rw	rw		rw					rw	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved	PLLN									PLL5M	PLL4M	PLL3M	PLL2M	PLL1M	PLL0M
	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bit 31:28 Reserved, must be kept at reset value.

Bits 27:24 **PLLQ**: Main PLL (PLL) division factor for USB OTG FS, SDIO and random number generator clocks

Set and cleared by software to control the frequency of USB OTG FS clock, the random number generator clock and the SDIO clock. These bits should be written only if PLL is disabled.

**Caution:** The USB OTG FS requires a 48 MHz clock to work correctly. The SDIO and the random number generator need a frequency lower than or equal to 48 MHz to work correctly.

USB OTG FS clock frequency = VCO frequency / PLLQ with  $2 \leq PLLQ \leq 15$

0000: PLLQ = 0, wrong configuration

0001: PLLQ = 1, wrong configuration

0010: PLLQ = 2

0011: PLLQ = 3

0100: PLLQ = 4

...

1111: PLLQ = 15

Bit 23 Reserved, must be kept at reset value.

Bit 22 **PLLSRC**: Main PLL(PLL) and audio PLL (PLL12S) entry clock source

Set and cleared by software to select PLL and PLL12S clock source. This bit can be written only when PLL and PLL12S are disabled.

0: HSI clock selected as PLL and PLL12S clock entry

1: HSE oscillator clock selected as PLL and PLL12S clock entry

Bits 21:18 Reserved, must be kept at reset value.

Bits 17:16 **PLLP**: Main PLL (PLL) division factor for main system clock

Set and cleared by software to control the frequency of the general PLL output clock. These bits can be written only if PLL is disabled.

**Caution:** The software has to set these bits correctly not to exceed 84 MHz on this domain.

PLL output clock frequency = VCO frequency / PLLP with PLLP = 2, 4, 6, or 8

00: PLLP = 2

01: PLLP = 4

10: PLLP = 6

11: PLLP = 8

Bits 14:6 **PLLN**: Main PLL (PLL) multiplication factor for VCO

Set and cleared by software to control the multiplication factor of the VCO. These bits can be written only when PLL is disabled. Only half-word and word accesses are allowed to write these bits.

**Caution:** The software has to set these bits correctly to ensure that the VCO output frequency is between 192 and 432 MHz. (check also [Section 6.3.20: RCC PLLI2S configuration register \(RCC\\_PLLI2SCFGR\)](#))

VCO output frequency = VCO input frequency × PLLN with  $192 \leq \text{PLLN} \leq 432$

00000000: PLLN = 0, wrong configuration

00000001: PLLN = 1, wrong configuration

...

...

110110000: PLLN = 432

110110001: PLLN = 433, wrong configuration

...

111111111: PLLN = 511, wrong configuration

Bits 5:0 **PLLM**: Division factor for the main PLL (PLL) and audio PLL (PLLI2S) input clock

Set and cleared by software to divide the PLL and PLLI2S input clock before the VCO. These bits can be written only when the PLL and PLLI2S are disabled.

**Caution:** The software has to set these bits correctly to ensure that the VCO input frequency ranges from 1 to 2 MHz. It is recommended to select a frequency of 2 MHz to limit PLL jitter.

VCO input frequency = PLL input clock frequency / PLLM with  $2 \leq \text{PLLM} \leq 63$

000000: PLLM = 0, wrong configuration

000001: PLLM = 1, wrong configuration

000010: PLLM = 2

000011: PLLM = 3

000100: PLLM = 4

...

111110: PLLM = 62

111111: PLLM = 63

### 6.3.3 RCC clock configuration register (RCC\_CFGR)

Address offset: 0x08

Reset value: 0x0000 0000

Access: 0 ≤ wait state ≤ 2, word, half-word and byte access

1 or 2 wait states inserted only if the access occurs during a clock source switch.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
MCO2		MCO2 PRE[2:0]			MCO1 PRE[2:0]			I2SSC R	MCO1		RTCPRE[4:0]				
rw		rw	rw	rw	rw	rw	rw	rw	rw		rw	rw	rw	rw	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
PPRE2[2:0]			PPRE1[2:0]			Reserved			HPRE[3:0]			SWS1	SWS0	SW1	SW0
rw	rw	rw	rw	rw	rw				rw	rw	rw	rw	r	r	rw

**Bits 31:30 MCO2[1:0]:** Microcontroller clock output 2

Set and cleared by software. Clock source selection may generate glitches on MCO2. It is highly recommended to configure these bits only after reset before enabling the external oscillators and the PLLs.

- 00: System clock (SYSCLK) selected
- 01: PLLI2S clock selected
- 10: HSE oscillator clock selected
- 11: PLL clock selected

**Bits 29:27 MCO2PRE:** MCO2 prescaler

Set and cleared by software to configure the prescaler of the MCO2. Modification of this prescaler may generate glitches on MCO2. It is highly recommended to change this prescaler only after reset before enabling the external oscillators and the PLLs.

- 0xx: no division
- 100: division by 2
- 101: division by 3
- 110: division by 4
- 111: division by 5

**Bits 26:24 MCO1PRE:** MCO1 prescaler

Set and cleared by software to configure the prescaler of the MCO1. Modification of this prescaler may generate glitches on MCO1. It is highly recommended to change this prescaler only after reset before enabling the external oscillators and the PLL.

- 0xx: no division
- 100: division by 2
- 101: division by 3
- 110: division by 4
- 111: division by 5

**Bit 23 I2SSRC:** I2S clock selection

Set and cleared by software. This bit allows to select the I2S clock source between the PLLI2S clock and the external clock. It is highly recommended to change this bit only after reset and before enabling the I2S module.

- 0: PLLI2S clock used as I2S clock source
- 1: External clock mapped on the I2S\_CKIN pin used as I2S clock source



Bits 22:21 **MCO1**: Microcontroller clock output 1

Set and cleared by software. Clock source selection may generate glitches on MCO1. It is highly recommended to configure these bits only after reset before enabling the external oscillators and PLL.

00: HSI clock selected

01: LSE oscillator selected

10: HSE oscillator clock selected

11: PLL clock selected

Bits 20:16 **RTCPRE**: HSE division factor for RTC clock

Set and cleared by software to divide the HSE clock input clock to generate a 1 MHz clock for RTC.

**Caution:** The software has to set these bits correctly to ensure that the clock supplied to the RTC is 1 MHz. These bits must be configured if needed before selecting the RTC clock source.

00000: no clock

00001: no clock

00010: HSE/2

00011: HSE/3

00100: HSE/4

...

11110: HSE/30

11111: HSE/31

Bits 15:13 **PPRE2**: APB high-speed prescaler (APB2)

Set and cleared by software to control APB high-speed clock division factor.

**Caution:** The software has to set these bits correctly not to exceed 84 MHz on this domain. The clocks are divided with the new prescaler factor from 1 to 16 AHB cycles after PPRE2 write.

0xx: AHB clock not divided

100: AHB clock divided by 2

101: AHB clock divided by 4

110: AHB clock divided by 8

111: AHB clock divided by 16

Bits 12:10 **PPRE1**: APB Low speed prescaler (APB1)

Set and cleared by software to control APB low-speed clock division factor.

**Caution:** The software has to set these bits correctly not to exceed 42 MHz on this domain. The clocks are divided with the new prescaler factor from 1 to 16 AHB cycles after PPRE1 write.

0xx: AHB clock not divided

100: AHB clock divided by 2

101: AHB clock divided by 4

110: AHB clock divided by 8

111: AHB clock divided by 16

Bits 9:8 Reserved, must be kept at reset value.



Bits 7:4 **HPRE**: AHB prescaler

Set and cleared by software to control AHB clock division factor.

**Caution:** The clocks are divided with the new prescaler factor from 1 to 16 AHB cycles after HPRE write.

**Caution:** The AHB clock frequency must be at least 25 MHz when the Ethernet is used.

0xxx: system clock not divided  
1000: system clock divided by 2  
1001: system clock divided by 4  
1010: system clock divided by 8  
1011: system clock divided by 16  
1100: system clock divided by 64  
1101: system clock divided by 128  
1110: system clock divided by 256  
1111: system clock divided by 512

Bits 3:2 **SWS**: System clock switch status

Set and cleared by hardware to indicate which clock source is used as the system clock.

00: HSI oscillator used as the system clock  
01: HSE oscillator used as the system clock  
10: PLL used as the system clock  
11: not applicable

Bits 1:0 **SW**: System clock switch

Set and cleared by software to select the system clock source.

Set by hardware to force the HSI selection when leaving the Stop or Standby mode or in case of failure of the HSE oscillator used directly or indirectly as the system clock.

00: HSI oscillator selected as system clock  
01: HSE oscillator selected as system clock  
10: PLL selected as system clock  
11: not allowed

### 6.3.4 RCC clock interrupt register (RCC\_CIR)

Address offset: 0x0C

Reset value: 0x0000 0000

Access: no wait state, word, half-word and byte access

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved								CSSC	Reserved	PLLI2S RDYC	PLL RDYC	HSE RDYC	HSI RDYC	LSE RDYC	LSI RDYC
								w		w	w	w	w	w	
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved	PLLI2S RDYIE	PLL RDYIE	HSE RDYIE	HSI RDYIE	LSE RDYIE	LSI RDYIE	CSSF	Reserved	PLLI2S RDYF	PLL RDYF	HSE RDYF	HSI RDYF	LSE RDYF	LSI RDYF	
	rw	rw	rw	rw	rw	rw	r		r	r	r	r	r	r	

Bits 31:24 Reserved, must be kept at reset value.

Bit 23 **CSSC**: Clock security system interrupt clear  
 This bit is set by software to clear the CSSF flag.  
 0: No effect  
 1: Clear CSSF flag

Bit 22 Reserved, must be kept at reset value.

Bit 21 **PLLI2SRDYC**: PLLI2S ready interrupt clear  
 This bit is set by software to clear the PLLI2SRDYF flag.  
 0: No effect  
 1: PLLI2SRDYF cleared

Bit 20 **PLLRDYC**: Main PLL(PLL) ready interrupt clear  
 This bit is set by software to clear the PLLRDYF flag.  
 0: No effect  
 1: PLLRDYF cleared

Bit 19 **HSERDYC**: HSE ready interrupt clear  
 This bit is set by software to clear the HSERDYF flag.  
 0: No effect  
 1: HSERDYF cleared

Bit 18 **HSIRDYC**: HSI ready interrupt clear  
 This bit is set software to clear the HSIRDYF flag.  
 0: No effect  
 1: HSIRDYF cleared

Bit 17 **LSERDYC**: LSE ready interrupt clear  
 This bit is set by software to clear the LSERDYF flag.  
 0: No effect  
 1: LSERDYF cleared

Bit 16 **LSIRDYC**: LSI ready interrupt clear  
 This bit is set by software to clear the LSIRDYF flag.  
 0: No effect  
 1: LSIRDYF cleared



Bits 15:14 Reserved, must be kept at reset value.

Bit 13 **PLLI2SRDYIE**: PLLI2S ready interrupt enable

Set and cleared by software to enable/disable interrupt caused by PLLI2S lock.

0: PLLI2S lock interrupt disabled

1: PLLI2S lock interrupt enabled

Bit 12 **PLLRDYIE**: Main PLL (PLL) ready interrupt enable

Set and cleared by software to enable/disable interrupt caused by PLL lock.

0: PLL lock interrupt disabled

1: PLL lock interrupt enabled

Bit 11 **HSERDYIE**: HSE ready interrupt enable

Set and cleared by software to enable/disable interrupt caused by the HSE oscillator stabilization.

0: HSE ready interrupt disabled

1: HSE ready interrupt enabled

Bit 10 **HSIRDYIE**: HSI ready interrupt enable

Set and cleared by software to enable/disable interrupt caused by the HSI oscillator stabilization.

0: HSI ready interrupt disabled

1: HSI ready interrupt enabled

Bit 9 **LSERDYIE**: LSE ready interrupt enable

Set and cleared by software to enable/disable interrupt caused by the LSE oscillator stabilization.

0: LSE ready interrupt disabled

1: LSE ready interrupt enabled

Bit 8 **LSIRDYIE**: LSI ready interrupt enable

Set and cleared by software to enable/disable interrupt caused by LSI oscillator stabilization.

0: LSI ready interrupt disabled

1: LSI ready interrupt enabled

Bit 7 **CSSF**: Clock security system interrupt flag

Set by hardware when a failure is detected in the HSE oscillator.

Cleared by software setting the CSSC bit.

0: No clock security interrupt caused by HSE clock failure

1: Clock security interrupt caused by HSE clock failure

Bit 6 Reserved, must be kept at reset value.

Bit 5 **PLLI2SRDYF**: PLLI2S ready interrupt flag

Set by hardware when the PLLI2S locks and PLLI2SRDYDIE is set.

Cleared by software setting the PLLRI2SDYC bit.

0: No clock ready interrupt caused by PLLI2S lock

1: Clock ready interrupt caused by PLLI2S lock

Bit 4 **PLLRDYF**: Main PLL (PLL) ready interrupt flag

Set by hardware when PLL locks and PLLRDYDIE is set.

Cleared by software setting the PLLRDYC bit.

0: No clock ready interrupt caused by PLL lock

1: Clock ready interrupt caused by PLL lock

- Bit 3 **HSERDYF**: HSE ready interrupt flag  
 Set by hardware when External High Speed clock becomes stable and HSERDYDIE is set.  
 Cleared by software setting the HSERDYC bit.  
 0: No clock ready interrupt caused by the HSE oscillator  
 1: Clock ready interrupt caused by the HSE oscillator
- Bit 2 **HSIRDYF**: HSI ready interrupt flag  
 Set by hardware when the Internal High Speed clock becomes stable and HSIRDYDIE is set.  
 Cleared by software setting the HSIRDYC bit.  
 0: No clock ready interrupt caused by the HSI oscillator  
 1: Clock ready interrupt caused by the HSI oscillator
- Bit 1 **LSERDYF**: LSE ready interrupt flag  
 Set by hardware when the External Low Speed clock becomes stable and LSE RDYDIE is set.  
 Cleared by software setting the LSE RDYC bit.  
 0: No clock ready interrupt caused by the LSE oscillator  
 1: Clock ready interrupt caused by the LSE oscillator
- Bit 0 **LSIRDYF**: LSI ready interrupt flag  
 Set by hardware when the internal low speed clock becomes stable and LSIRDYDIE is set.  
 Cleared by software setting the LSIRDYC bit.  
 0: No clock ready interrupt caused by the LSI oscillator  
 1: Clock ready interrupt caused by the LSI oscillator

### 6.3.5 RCC AHB1 peripheral reset register (RCC\_AHB1RSTR)

Address offset: 0x10

Reset value: 0x0000 0000

Access: no wait state, word, half-word and byte access.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved									DMA2 RST	DMA1 RST	Reserved				
									rw	rw					
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved			CRCRST	Reserved				GPIOH RST	Reserved		GPIOE RST	GPIOD RST	GPIOC RST	GPIOB RST	GPIOA RST
			rw					rw			rw	rw	rw	rw	rw

Bits 31:23 Reserved, must be kept at reset value.

- Bit 22 **DMA2RST**: DMA2 reset  
 Set and cleared by software.  
 0: does not reset DMA2  
 1: resets DMA2

- Bit 21 **DMA1RST**: DMA1 reset  
 Set and cleared by software.  
 0: does not reset DMA1  
 1: resets DMA1

Bits 20:13 Reserved, must be kept at reset value.



Bit 12 **CRCRST**: CRC reset  
Set and cleared by software.  
0: does not reset CRC  
1: resets CRC

Bits 11:8 Reserved, must be kept at reset value.

Bit 7 **GPIOHRST**: IO port H reset  
Set and cleared by software.  
0: does not reset IO port H  
1: resets IO port H

Bits 6:5 Reserved, must be kept at reset value.

Bit 4 **GPIOERST**: IO port E reset  
Set and cleared by software.  
0: does not reset IO port E  
1: resets IO port E

Bit 3 **GPIODRST**: IO port D reset  
Set and cleared by software.  
0: does not reset IO port D  
1: resets IO port D

Bit 2 **GPIOCRST**: IO port C reset  
Set and cleared by software.  
0: does not reset IO port C  
1: resets IO port C

Bit 1 **GPIOBRST**: IO port B reset  
Set and cleared by software.  
0: does not reset IO port B  
1: resets IO port B

Bit 0 **GPIOARST**: IO port A reset  
Set and cleared by software.  
0: does not reset IO port A  
1: resets IO port A

### 6.3.6 RCC AHB2 peripheral reset register (RCC\_AHB2RSTR)

Address offset: 0x14

Reset value: 0x0000 0000

Access: no wait state, word, half-word and byte access

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	
Reserved																
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
Reserved								OTGFS RST	Reserved							
								rw								

Bits 31:8 Reserved, must be kept at reset value.

Bit 6:0 Reserved, must be kept at reset value.

### 6.3.7 RCC APB1 peripheral reset register for (RCC\_APB1RSTR)

Address offset: 0x20

Reset value: 0x0000 0000

Access: no wait state, word, half-word and byte access.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	
Reserved			PWR RST	Reserved					I2C3 RST	I2C2 RST	I2C1 RST	Reserved			USART2 RST	Reser- ved
			rw						rw	rw	rw				rw	
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
SPI3 RST	SPI2 RST	Reserved		WWDG RST	Reserved							TIM5 RST	TIM4 RST	TIM3 RST	TIM2 RST	
rw	rw			rw								rw	rw	rw	rw	

Bits 31:29 Reserved, must be kept at reset value.

Bit 28 **PWRRST**: Power interface reset

Set and cleared by software.

0: does not reset the power interface

1: resets the power interface

Bits 27:24 Reserved, must be kept at reset value.

Bit 23 **I2C3RST**: I2C3 reset

Set and cleared by software.

0: does not reset I2C3

1: resets I2C3

Bit 22 **I2C2RST**: I2C2 reset

Set and cleared by software.

0: does not reset I2C2

1: resets I2C2

- Bit 21 **I2C1RST**: I2C1 reset  
Set and cleared by software.  
0: does not reset I2C1  
1: resets I2C1
- Bits 20:18 Reserved, must be kept at reset value.
- Bit 17 **USART2RST**: USART2 reset  
Set and cleared by software.  
0: does not reset USART2  
1: resets USART2
- Bit 16 Reserved, must be kept at reset value.
- Bit 15 **SPI3RST**: SPI3 reset  
Set and cleared by software.  
0: does not reset SPI3  
1: resets SPI3
- Bit 14 **SPI2RST**: SPI2 reset  
Set and cleared by software.  
0: does not reset SPI2  
1: resets SPI2
- Bits 13:12 Reserved, must be kept at reset value.
- Bit 11 **WWDGRST**: Window watchdog reset  
Set and cleared by software.  
0: does not reset the window watchdog  
1: resets the window watchdog
- Bits 10:4 Reserved, must be kept at reset value.
- Bit 3 **TIM5RST**: TIM5 reset  
Set and cleared by software.  
0: does not reset TIM5  
1: resets TIM5
- Bit 2 **TIM4RST**: TIM4 reset  
Set and cleared by software.  
0: does not reset TIM4  
1: resets TIM4
- Bit 1 **TIM3RST**: TIM3 reset  
Set and cleared by software.  
0: does not reset TIM3  
1: resets TIM3
- Bit 0 **TIM2RST**: TIM2 reset  
Set and cleared by software.  
0: does not reset TIM2  
1: resets TIM2

### 6.3.8 RCC APB2 peripheral reset register (RCC\_APB2RSTR)

Address offset: 0x24

Reset value: 0x0000 0000

Access: no wait state, word, half-word and byte access.

31											30											29											28											27											26											25											24											23											22											21											20											19											18											17											16																																																																										
Reserved																											TIM11 RST											TIM10 RST											TIM9 RST																																																																																																																																																																																														
rw																											rw											rw											rw																																																																																																																																																																																														
15															14															13															12															11															10															9															8															7															6															5															4															3															2															1															0														
Reserved															SYSCFG RST															SPI4 RST															SPI1 RST															SDIO RST															Reserved															ADC1 RST															Reserved															USART6 RST															USART1 RST															Reserved															TIM1 RST																																																																										
rw															rw															rw															rw															rw															rw															rw															rw															rw															rw															rw																																																																																									

Bits 31:19 Reserved, must be kept at reset value.

Bit 18 **TIM11RST**: TIM11 reset  
 Set and cleared by software.  
 0: does not reset TIM11  
 1: resets TIM11

Bit 17 **TIM10RST**: TIM10 reset  
 Set and cleared by software.  
 0: does not reset TIM10  
 1: resets TIM10

Bit 16 **TIM9RST**: TIM9 reset  
 Set and cleared by software.  
 0: does not reset TIM9  
 1: resets TIM9

Bit 15 Reserved, must be kept at reset value.

Bit 14 **SYSCFGRST**: System configuration controller reset  
 Set and cleared by software.  
 0: does not reset the System configuration controller  
 1: resets the System configuration controller

Bit 13 **SPI4RST**: SPI4 reset  
 Set and reset by software.  
 0: does not reset SPI4  
 1: resets SPI4

Bit 12 **SPI1RST**: SPI1 reset  
 Set and cleared by software.  
 0: does not reset SPI1  
 1: resets SPI1

Bit 11 **SDIORST**: SDIO reset  
 Set and cleared by software.  
 0: does not reset the SDIO module  
 1: resets the SDIO module

Bits 10:9 Reserved, must be kept at reset value.





- Bit 8 **ADC1RST**: ADC interface reset  
Set and cleared by software.  
0: does not reset the ADC interface  
1: resets the ADC interface
- Bits 7:6 Reserved, must be kept at reset value.
- Bit 5 **USART6RST**: USART6 reset  
Set and cleared by software.  
0: does not reset USART6  
1: resets USART6
- Bit 4 **USART1RST**: USART1 reset  
Set and cleared by software.  
0: does not reset USART1  
1: resets USART1
- Bits 3:1 Reserved, must be kept at reset value.
- Bit 0 **TIM1RST**: TIM1 reset  
Set and cleared by software.  
0: does not reset TIM1  
1: resets TIM1

### 6.3.9 RCC AHB1 peripheral clock enable register (RCC\_AHB1ENR)

Address offset: 0x30

Reset value: 0x0000 0000

Access: no wait state, word, half-word and byte access.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved									DMA2EN	DMA1EN	Reserved				
									rw	rw					
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved			CRCEN	Reserved				GPIOH EN	Reserved		GPIOEEN	GIOD EN	GPIOC EN	GPIOB EN	GPIOA EN
			rw					rw			rw	rw	rw	rw	rw

Bits 31:23 Reserved, must be kept at reset value.

Bit 22 **DMA2EN**: DMA2 clock enable  
 Set and cleared by software.  
 0: DMA2 clock disabled  
 1: DMA2 clock enabled

Bit 21 **DMA1EN**: DMA1 clock enable  
 Set and cleared by software.  
 0: DMA1 clock disabled  
 1: DMA1 clock enabled

Bits 20:13 Reserved, must be kept at reset value.

Bit 12 **CRCEN**: CRC clock enable  
 Set and cleared by software.  
 0: CRC clock disabled  
 1: CRC clock enabled

Bits 11:8 Reserved, must be kept at reset value.

Bit 7 **GPIOHEN**: IO port H clock enable  
 Set and reset by software.  
 0: IO port H clock disabled  
 1: IO port H clock enabled

Bits 6:5 Reserved, must be kept at reset value.

Bit 4 **GPIOEEN**: IO port E clock enable  
 Set and cleared by software.  
 0: IO port E clock disabled  
 1: IO port E clock enabled

Bit 3 **GIODEN**: IO port D clock enable  
 Set and cleared by software.  
 0: IO port D clock disabled  
 1: IO port D clock enabled

Bit 2 **GPIOCEN**: IO port C clock enable  
 Set and cleared by software.  
 0: IO port C clock disabled  
 1: IO port C clock enabled

Bit 1 **GPIOBEN**: IO port B clock enable  
 Set and cleared by software.  
 0: IO port B clock disabled  
 1: IO port B clock enabled

Bit 0 **GPIOAEN**: IO port A clock enable  
 Set and cleared by software.  
 0: IO port A clock disabled  
 1: IO port A clock enabled

### 6.3.10 RCC AHB2 peripheral clock enable register (RCC\_AHB2ENR)

Address offset: 0x34

Reset value: 0x0000 0000

Access: no wait state, word, half-word and byte access.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	
Reserved																
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
Reserved								OTGFS EN	Reserved							
								rw								

Bits 31:8 Reserved, must be kept at reset value.

Bit 7 **OTGFSEN**: USB OTG FS clock enable  
 Set and cleared by software.  
 0: USB OTG FS clock disabled  
 1: USB OTG FS clock enabled

Bits 6:0 Reserved, must be kept at reset value.

### 6.3.11 RCC APB1 peripheral clock enable register (RCC\_APB1ENR)

Address offset: 0x40

Reset value: 0x0000 0000

Access: no wait state, word, half-word and byte access.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	
Reserved			PWR EN	Reserved					I2C3 EN	I2C2 EN	I2C1 EN	Reserved			USART2 EN	Reser- ved
			rw						rw	rw	rw				rw	
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
SPI3 EN	SPI2 EN	Reserved		WWDG EN	Reserved						TIM5 EN	TIM4 EN	TIM3 EN	TIM2 EN		
rw	rw			rw							rw	rw	rw	rw		

Bits 31:29 Reserved, must be kept at reset value.

- Bit 28 **PWREN**: Power interface clock enable  
Set and cleared by software.  
0: Power interface clock disabled  
1: Power interface clock enable

Bits 27:24 Reserved, must be kept at reset value.

- Bit 23 **I2C3EN**: I2C3 clock enable  
Set and cleared by software.  
0: I2C3 clock disabled  
1: I2C3 clock enabled

- Bit 22 **I2C2EN**: I2C2 clock enable  
Set and cleared by software.  
0: I2C2 clock disabled  
1: I2C2 clock enabled

- Bit 21 **I2C1EN**: I2C1 clock enable  
Set and cleared by software.  
0: I2C1 clock disabled  
1: I2C1 clock enabled

Bits 20:18 Reserved, must be kept at reset value.

- Bit 17 **USART2EN**: USART2 clock enable  
Set and cleared by software.  
0: USART2 clock disabled  
1: USART2 clock enabled

Bit 16 Reserved, must be kept at reset value.

- Bit 15 **SPI3EN**: SPI3 clock enable  
Set and cleared by software.  
0: SPI3 clock disabled  
1: SPI3 clock enabled

- Bit 14 **SPI2EN**: SPI2 clock enable  
Set and cleared by software.  
0: SPI2 clock disabled  
1: SPI2 clock enabled

Bits 13:12 Reserved, must be kept at reset value.

- Bit 11 **WWDGEN**: Window watchdog clock enable  
Set and cleared by software.  
0: Window watchdog clock disabled  
1: Window watchdog clock enabled

Bits 10:4 Reserved, must be kept at reset value.

- Bit 3 **TIM5EN**: TIM5 clock enable  
Set and cleared by software.  
0: TIM5 clock disabled  
1: TIM5 clock enabled

- Bit 2 **TIM4EN**: TIM4 clock enable
  - Set and cleared by software.
  - 0: TIM4 clock disabled
  - 1: TIM4 clock enabled
  
- Bit 1 **TIM3EN**: TIM3 clock enable
  - Set and cleared by software.
  - 0: TIM3 clock disabled
  - 1: TIM3 clock enabled
  
- Bit 0 **TIM2EN**: TIM2 clock enable
  - Set and cleared by software.
  - 0: TIM2 clock disabled
  - 1: TIM2 clock enabled

### 6.3.12 RCC APB2 peripheral clock enable register (RCC\_APB2ENR)

Address offset: 0x44

Reset value: 0x0000 0000

Access: no wait state, word, half-word and byte access.

Reserved															TIM11 EN	TIM10 EN	TIM9 EN
															rw	rw	rw
31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16		
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0		
Reser-ved	SYSCF G EN	SPI4EN	SPI1 EN	SDIO EN	Reserved			ADC1 EN	Reserved			USART6 EN	USART1 EN	Reserved		TIM1 EN	
	rw	rw	rw	rw				rw				rw	rw			rw	

Bits 31:19 Reserved, must be kept at reset value.

Bit 18 **TIM11EN**: TIM11 clock enable  
 Set and cleared by software.  
 0: TIM11 clock disabled  
 1: TIM11 clock enabled

Bit 17 **TIM10EN**: TIM10 clock enable  
 Set and cleared by software.  
 0: TIM10 clock disabled  
 1: TIM10 clock enabled

Bit 16 **TIM9EN**: TIM9 clock enable  
 Set and cleared by software.  
 0: TIM9 clock disabled  
 1: TIM9 clock enabled

Bit 15 Reserved, must be kept at reset value.

Bit 14 **SYSCFGEN**: System configuration controller clock enable  
 Set and cleared by software.  
 0: System configuration controller clock disabled  
 1: System configuration controller clock enabled

Bit 13 **SPI4EN**: SPI4 clock enable  
 Set and reset by software.  
 0: SPI4 clock disabled  
 1: SPI4 clock enable

Bit 12 **SPI1EN**: SPI1 clock enable  
 Set and cleared by software.  
 0: SPI1 clock disabled  
 1: SPI1 clock enabled

Bit 11 **SDIOEN**: SDIO clock enable  
 Set and cleared by software.  
 0: SDIO module clock disabled  
 1: SDIO module clock enabled

Bit 8 **ADC1EN**: ADC1 clock enable  
Set and cleared by software.  
0: ADC1 clock disabled  
1: ADC1 clock disabled

Bits 7:6 Reserved, must be kept at reset value.

Bit 5 **USART6EN**: USART6 clock enable  
Set and cleared by software.  
0: USART6 clock disabled  
1: USART6 clock enabled

Bit 4 **USART1EN**: USART1 clock enable  
Set and cleared by software.  
0: USART1 clock disabled  
1: USART1 clock enabled

Bits 3:1 Reserved, must be kept at reset value.

Bit 0 **TIM1EN**: TIM1 clock enable  
Set and cleared by software.  
0: TIM1 clock disabled  
1: TIM1 clock enabled

### 6.3.13 RCC AHB1 peripheral clock enable in low power mode register (RCC\_AHB1LPENR)

Address offset: 0x50

Reset value: 0x0061 900F

Access: no wait state, word, half-word and byte access.

31															30															29															28															27															26															25															24															23															22															21															20															19															18															17															16														
Reserved																						DMA2 LPEN					DMA1 LPEN					Reserved															SRAM1 LPEN																																																																																																																																																																																																
rw										rw																									rw																																																																																																																																																																																																												
15															14															13															12															11															10															9															8															7															6															5															4															3															2															1															0														
FLITF LPEN					Reserved										CRC LPEN					Reserved															GPIOH LPEN					Reserved										GPIOE LPEN					GPIOD LPEN					GPIOC LPEN					GPIOB LPEN					GPIOA LPEN																																																																																																																																																																									
rw															rw																				rw															rw					rw					rw					rw																																																																																																																																																																														

Bits 31:23 Reserved, must be kept at reset value.

Bit 22 **DMA2LPEN**: DMA2 clock enable during Sleep mode  
 Set and cleared by software.  
 0: DMA2 clock disabled during Sleep mode  
 1: DMA2 clock enabled during Sleep mode

Bit 21 **DMA1LPEN**: DMA1 clock enable during Sleep mode  
 Set and cleared by software.  
 0: DMA1 clock disabled during Sleep mode  
 1: DMA1 clock enabled during Sleep mode

Bits 20:17 Reserved, must be kept at reset value.

Bit 16 **SRAM1LPEN**: SRAM1 interface clock enable during Sleep mode  
 Set and cleared by software.  
 0: SRAM1 interface clock disabled during Sleep mode  
 1: SRAM1 interface clock enabled during Sleep mode

Bit 15 **FLITFLPEN**: Flash interface clock enable during Sleep mode  
 Set and cleared by software.  
 0: Flash interface clock disabled during Sleep mode  
 1: Flash interface clock enabled during Sleep mode

Bits 14:13 Reserved, must be kept at reset value.

Bit 12 **CRCLPEN**: CRC clock enable during Sleep mode  
 Set and cleared by software.  
 0: CRC clock disabled during Sleep mode  
 1: CRC clock enabled during Sleep mode

Bits 11:8 Reserved, must be kept at reset value.

Bit 7 **GPIOHLPEN**: IO port H clock enable during sleep mode  
 Set and reset by software.  
 0: IO port H clock disabled during sleep mode  
 1: IO port H clock enabled during sleep mode

Bits 6:5 Reserved, must be kept at reset value.





- Bit 4 **GPIOELPEN**: IO port E clock enable during Sleep mode  
Set and cleared by software.  
0: IO port E clock disabled during Sleep mode  
1: IO port E clock enabled during Sleep mode
- Bit 3 **GPIODLPEN**: IO port D clock enable during Sleep mode  
Set and cleared by software.  
0: IO port D clock disabled during Sleep mode  
1: IO port D clock enabled during Sleep mode
- Bit 2 **GPIOCLPEN**: IO port C clock enable during Sleep mode  
Set and cleared by software.  
0: IO port C clock disabled during Sleep mode  
1: IO port C clock enabled during Sleep mode
- Bit 1 **GPIOBLPEN**: IO port B clock enable during Sleep mode  
Set and cleared by software.  
0: IO port B clock disabled during Sleep mode  
1: IO port B clock enabled during Sleep mode
- Bit 0 **GPIOALPEN**: IO port A clock enable during sleep mode  
Set and cleared by software.  
0: IO port A clock disabled during Sleep mode  
1: IO port A clock enabled during Sleep mode

### 6.3.14 RCC AHB2 peripheral clock enable in low power mode register (RCC\_AHB2LPENR)

Address offset: 0x54

Reset value: 0x0000 0080

Access: no wait state, word, half-word and byte access.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	
Reserved																
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
Reserved								OTGFS LPEN	Reserved							
								rw								

Bits 31:8 Reserved, must be kept at reset value.

- Bit 7 **OTGFSLPEN**: USB OTG FS clock enable during Sleep mode  
Set and cleared by software.  
0: USB OTG FS clock disabled during Sleep mode  
1: USB OTG FS clock enabled during Sleep mode

Bits 6:0 Reserved, must be kept at reset value.

### 6.3.15 RCC APB1 peripheral clock enable in low power mode register (RCC\_APB1LPENR)

Address offset: 0x60

Reset value: 0x10E2 C80F

Access: no wait state, word, half-word and byte access.

Reserved				PWR LPEN	Reserved				I2C3 LPEN	I2C2 LPEN	I2C1 LPEN	Reserved				USART2 LPEN	Reserved
				rw					rw	rw	rw					rw	
31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16		
SPI3 LPEN		SPI2 LPEN		Reserved				WWDG LPEN	Reserved				TIM5 LPEN	TIM4 LPEN	TIM3 LPEN	TIM2 LPEN	
rw		rw						rw					rw	rw	rw	rw	
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0		

Bits 31:29 Reserved, must be kept at reset value.

Bit 28 **PWRLPEN**: Power interface clock enable during Sleep mode

Set and cleared by software.

0: Power interface clock disabled during Sleep mode

1: Power interface clock enabled during Sleep mode

Bits 27:24 Reserved, must be kept at reset value.

Bit 23 **I2C3LPEN**: I2C3 clock enable during Sleep mode

Set and cleared by software.

0: I2C3 clock disabled during Sleep mode

1: I2C3 clock enabled during Sleep mode

Bit 22 **I2C2LPEN**: I2C2 clock enable during Sleep mode

Set and cleared by software.

0: I2C2 clock disabled during Sleep mode

1: I2C2 clock enabled during Sleep mode

Bit 21 **I2C1LPEN**: I2C1 clock enable during Sleep mode

Set and cleared by software.

0: I2C1 clock disabled during Sleep mode

1: I2C1 clock enabled during Sleep mode

Bits 20:18 Reserved, must be kept at reset value.

Bit 17 **USART2LPEN**: USART2 clock enable during Sleep mode

Set and cleared by software.

0: USART2 clock disabled during Sleep mode

1: USART2 clock enabled during Sleep mode

Bit 16 Reserved, must be kept at reset value.

Bit 15 **SPI3LPEN**: SPI3 clock enable during Sleep mode

Set and cleared by software.

0: SPI3 clock disabled during Sleep mode

1: SPI3 clock enabled during Sleep mode

Bit 14 **SPI2LPEN**: SPI2 clock enable during Sleep mode

Set and cleared by software.

0: SPI2 clock disabled during Sleep mode

1: SPI2 clock enabled during Sleep mode

Bits 13:12 Reserved, must be kept at reset value.

Bit 11 **WWDGLPEN**: Window watchdog clock enable during Sleep mode

Set and cleared by software.

0: Window watchdog clock disabled during sleep mode

1: Window watchdog clock enabled during sleep mode

Bits 10:4 Reserved, must be kept at reset value.

Bit 3 **TIM5LPEN**: TIM5 clock enable during Sleep mode

Set and cleared by software.

0: TIM5 clock disabled during Sleep mode

1: TIM5 clock enabled during Sleep mode

Bit 2 **TIM4LPEN**: TIM4 clock enable during Sleep mode

Set and cleared by software.

0: TIM4 clock disabled during Sleep mode

1: TIM4 clock enabled during Sleep mode

Bit 1 **TIM3LPEN**: TIM3 clock enable during Sleep mode

Set and cleared by software.

0: TIM3 clock disabled during Sleep mode

1: TIM3 clock enabled during Sleep mode

Bit 0 **TIM2LPEN**: TIM2 clock enable during Sleep mode

Set and cleared by software.

0: TIM2 clock disabled during Sleep mode

1: TIM2 clock enabled during Sleep mode

### 6.3.16 RCC APB2 peripheral clock enabled in low power mode register (RCC\_APB2LPENR)

Address offset: 0x64

Reset value: 0x0007 7930

Access: no wait state, word, half-word and byte access.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	
Reserved													TIM11 LPEN	TIM10 LPEN	TIM9 LPEN	
													rw	rw	rw	
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
Reser- ved	SYSC FG LPEN	SPI4LP EN	SPI1 LPEN	SDIO LPEN	Reserved			ADC1 LPEN	Reserved			USART6 LPEN	USART1 LPEN	Reserved		TIM1 LPEN
	rw	rw	rw	rw				rw				rw	rw			rw

Bits 31:19 Reserved, must be kept at reset value.

**Bit 18 TIM11LPEN:** TIM11 clock enable during Sleep mode  
 Set and cleared by software.  
 0: TIM11 clock disabled during Sleep mode  
 1: TIM11 clock enabled during Sleep mode

**Bit 17 TIM10LPEN:** TIM10 clock enable during Sleep mode  
 Set and cleared by software.  
 0: TIM10 clock disabled during Sleep mode  
 1: TIM10 clock enabled during Sleep mode

**Bit 16 TIM9LPEN:** TIM9 clock enable during sleep mode  
 Set and cleared by software.  
 0: TIM9 clock disabled during Sleep mode  
 1: TIM9 clock enabled during Sleep mode

Bit 15 Reserved, must be kept at reset value.

**Bit 14 SYSCFGLPEN:** System configuration controller clock enable during Sleep mode  
 Set and cleared by software.  
 0: System configuration controller clock disabled during Sleep mode  
 1: System configuration controller clock enabled during Sleep mode

**Bit 13 SPI4LPEN:** SPI4 clock enable during sleep mode  
 Set and reset by software.  
 0: SPI4 clock disabled during sleep mode  
 1: SPI4 clock enabled during sleep mode

**Bit 12 SPI1LPEN:** SPI1 clock enable during Sleep mode  
 Set and cleared by software.  
 0: SPI1 clock disabled during Sleep mode  
 1: SPI1 clock enabled during Sleep mode

**Bit 11 SDIOLPEN:** SDIO clock enable during Sleep mode  
 Set and cleared by software.  
 0: SDIO module clock disabled during Sleep mode  
 1: SDIO module clock enabled during Sleep mode

Bits 10:9 Reserved, must be kept at reset value.

Bit 8 **ADC1LPEN**: ADC1 clock enable during Sleep mode

Set and cleared by software.

0: ADC1 clock disabled during Sleep mode

1: ADC1 clock disabled during Sleep mode

Bits 7:6 Reserved, must be kept at reset value.

Bit 5 **USART6LPEN**: USART6 clock enable during Sleep mode

Set and cleared by software.

0: USART6 clock disabled during Sleep mode

1: USART6 clock enabled during Sleep mode

Bit 4 **USART1LPEN**: USART1 clock enable during Sleep mode

Set and cleared by software.

0: USART1 clock disabled during Sleep mode

1: USART1 clock enabled during Sleep mode

Bits 3:1 Reserved, must be kept at reset value.

Bit 0 **TIM1LPEN**: TIM1 clock enable during Sleep mode

Set and cleared by software.

0: TIM1 clock disabled during Sleep mode

1: TIM1 clock enabled during Sleep mode

### 6.3.17 RCC Backup domain control register (RCC\_BDCR)

Address offset: 0x70

Reset value: 0x0000 0000, reset by Backup domain reset.

Access:  $0 \leq \text{wait state} \leq 3$ , word, half-word and byte access

Wait states are inserted in case of successive accesses to this register.

The LSEON, LSEBYP, RTCSEL and RTCEN bits in the *RCC Backup domain control register (RCC\_BDCR)* are in the Backup domain. As a result, after Reset, these bits are write-protected and the DBP bit in the *PWR power control register (PWR\_CR)* has to be set before these can be modified. Refer to *Section 5.1.2 on page 72* for further information. These bits are only reset after a Backup domain Reset (see *Section 6.1.3: Backup domain reset*). Any internal or external Reset will not have any effect on these bits.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	
Reserved															BDRST	
															rw	
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
RTCEN	Reserved						RTCSEL[1:0]		Reserved					LSEBYP	LSERDY	LSEON
rw							rw	rw						rw	r	rw

Bits 31:17 Reserved, must be kept at reset value.

Bit 16 **BDRST**: Backup domain software reset

Set and cleared by software.

0: Reset not activated

1: Resets the entire Backup domain

Bit 15 **RTCEN**: RTC clock enable

Set and cleared by software.

0: RTC clock disabled

1: RTC clock enabled

Bits 14:10 Reserved, must be kept at reset value.

Bits 9:8 **RTCSEL[1:0]**: RTC clock source selection

Set by software to select the clock source for the RTC. Once the RTC clock source has been selected, it cannot be changed anymore unless the Backup domain is reset. The BDRST bit can be used to reset them.

00: No clock

01: LSE oscillator clock used as the RTC clock

10: LSI oscillator clock used as the RTC clock

11: HSE oscillator clock divided by a programmable prescaler (selection through the RTCPRE[4:0] bits in the RCC clock configuration register (RCC\_CFGR)) used as the RTC clock

Bits 7:3 Reserved, must be kept at reset value.

Bit 2 **LSEBYP**: External low-speed oscillator bypass

Set and cleared by software to bypass oscillator in debug mode. This bit can be written only when the LSE clock is disabled.

0: LSE oscillator not bypassed

1: LSE oscillator bypassed

- Bit 1 **LSERDY**: External low-speed oscillator ready  
 Set and cleared by hardware to indicate when the external 32 kHz oscillator is stable. After the LSEON bit is cleared, LSERDY goes low after 6 external low-speed oscillator clock cycles.  
 0: LSE clock not ready  
 1: LSE clock ready
- Bit 0 **LSEON**: External low-speed oscillator enable  
 Set and cleared by software.  
 0: LSE clock OFF  
 1: LSE clock ON

### 6.3.18 RCC clock control & status register (RCC\_CSR)

Address offset: 0x74

Reset value: 0x0E00 0000, reset by system reset, except reset flags by power reset only.

Access: 0 ≤ wait state ≤ 3, word, half-word and byte access

Wait states are inserted in case of successive accesses to this register.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16		
LPWR RSTF	WWDG RSTF	IWDG RSTF	SFT RSTF	POR RSTF	PIN RSTF	BORRS TF	RMVF	Reserved									
r	r	r	r	r	r	r	rt_w										
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0		
Reserved													LSIRDY	LSION			
													r	rw			

- Bit 31 **LPWRRSTF**: Low-power reset flag  
 Set by hardware when a Low-power management reset occurs.  
 Cleared by writing to the RMVF bit.  
 0: No Low-power management reset occurred  
 1: Low-power management reset occurred  
 For further information on Low-power management reset, refer to [Low-power management reset](#).
- Bit 30 **WWDGRSTF**: Window watchdog reset flag  
 Set by hardware when a window watchdog reset occurs.  
 Cleared by writing to the RMVF bit.  
 0: No window watchdog reset occurred  
 1: Window watchdog reset occurred
- Bit 29 **IWDGRSTF**: Independent watchdog reset flag  
 Set by hardware when an independent watchdog reset from V<sub>DD</sub> domain occurs.  
 Cleared by writing to the RMVF bit.  
 0: No watchdog reset occurred  
 1: Watchdog reset occurred
- Bit 28 **SFTRSTF**: Software reset flag  
 Set by hardware when a software reset occurs.  
 Cleared by writing to the RMVF bit.  
 0: No software reset occurred  
 1: Software reset occurred

- Bit 27 **PORRSTF**: POR/PDR reset flag  
Set by hardware when a POR/PDR reset occurs.  
Cleared by writing to the RMVF bit.  
0: No POR/PDR reset occurred  
1: POR/PDR reset occurred
- Bit 26 **PINRSTF**: PIN reset flag  
Set by hardware when a reset from the NRST pin occurs.  
Cleared by writing to the RMVF bit.  
0: No reset from NRST pin occurred  
1: Reset from NRST pin occurred
- Bit 25 **BORRSTF**: BOR reset flag  
Cleared by software by writing the RMVF bit.  
Set by hardware when a POR/PDR or BOR reset occurs.  
0: No POR/PDR or BOR reset occurred  
1: POR/PDR or BOR reset occurred
- Bit 24 **RMVF**: Remove reset flag  
Set by software to clear the reset flags.  
0: No effect  
1: Clear the reset flags
- Bits 23:2 Reserved, must be kept at reset value.
- Bit 1 **LSIRDY**: Internal low-speed oscillator ready  
Set and cleared by hardware to indicate when the internal RC 40 kHz oscillator is stable.  
After the LSION bit is cleared, LSIRDY goes low after 3 LSI clock cycles.  
0: LSI RC oscillator not ready  
1: LSI RC oscillator ready
- Bit 0 **LSION**: Internal low-speed oscillator enable  
Set and cleared by software.  
0: LSI RC oscillator OFF  
1: LSI RC oscillator ON



### 6.3.19 RCC spread spectrum clock generation register (RCC\_SSCGR)

Address offset: 0x80

Reset value: 0x0000 0000

Access: no wait state, word, half-word and byte access.

The spread spectrum clock generation is available only for the main PLL.

The RCC\_SSCGR register must be written either before the main PLL is enabled or after the main PLL disabled.

*Note:* For full details about PLL spread spectrum clock generation (SSCG) characteristics, refer to the “Electrical characteristics” section in your device datasheet.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
SSCG EN	SPREASEL	Reserved			INCSTEP										
rw	rw			rw	rw	rw		rw	rw	rw	rw	rw	rw	rw	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
INCSTEP			MODPER												
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bit 31 **SSCGEN**: Spread spectrum modulation enable  
 Set and cleared by software.  
 0: Spread spectrum modulation DISABLE. (To write after clearing CR[24]=PLLON bit)  
 1: Spread spectrum modulation ENABLE. (To write before setting CR[24]=PLLON bit)

Bit 30 **SPREASEL**: Spread Select  
 Set and cleared by software.  
 To write before to set CR[24]=PLLON bit.  
 0: Center spread  
 1: Down spread

Bits 29:28 Reserved, must be kept at reset value.

Bits 27:13 **INCSTEP**: Incrementation step  
 Set and cleared by software. To write before setting CR[24]=PLLON bit.  
 Configuration input for modulation profile amplitude.

Bits 12:0 **MODPER**: Modulation period  
 Set and cleared by software. To write before setting CR[24]=PLLON bit.  
 Configuration input for modulation profile period.

### 6.3.20 RCC PLLI2S configuration register (RCC\_PLLI2SCFGR)

Address offset: 0x84

Reset value: 0x2400 3000

Access: no wait state, word, half-word and byte access.

This register is used to configure the PLLI2S clock outputs according to the formulas:

- $f_{(VCO\ clock)} = f_{(PLLI2S\ clock\ input)} \times (PLLI2SN / PLLM)$
- $f_{(PLL\ I2S\ clock\ output)} = f_{(VCO\ clock)} / PLLI2SR$

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved	PLLI2S R2	PLLI2S R1	PLLI2S R0	Reserved											
	rw	rw	rw												
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved	PLLI2SN 8	PLLI2SN 7	PLLI2SN 6	PLLI2SN 5	PLLI2SN 4	PLLI2SN 3	PLLI2SN 2	PLLI2SN 1	PLLI2S N0	Reserved					
	rw	rw	rw	rw	rw	rw	rw	rw	rw						

Bit 31 Reserved, must be kept at reset value.

Bits 30:28 **PLLI2SR**: PLLI2S division factor for I2S clocks

Set and cleared by software to control the I2S clock frequency. These bits should be written only if the PLLI2S is disabled. The factor must be chosen in accordance with the prescaler values inside the I2S peripherals, to reach 0.3% error when using standard crystals and 0% error with audio crystals. For more information about I2S clock frequency and precision, refer to [Section 20.4.4: Clock generator](#) in the I2S chapter.

**Caution:** The I2Ss requires a frequency lower than or equal to 192 MHz to work correctly.

I2S clock frequency = VCO frequency / PLLR with  $2 \leq PLLR \leq 7$

000: PLLR = 0, wrong configuration

001: PLLR = 1, wrong configuration

010: PLLR = 2

...

111: PLLR = 7

Bits 27:15 Reserved, must be kept at reset value.

Bits 14:6 **PLLI2SN**: PLLI2S multiplication factor for VCO

Set and cleared by software to control the multiplication factor of the VCO. These bits can be written only when the PLLI2S is disabled. Only half-word and word accesses are allowed to write these bits.

**Caution:** The software has to set these bits correctly to ensure that the VCO output frequency is between 192 and 432 MHz. With VCO input frequency ranges from 1 to 2 MHz (refer to [Figure 13](#) and divider factor M of the [RCC PLL configuration register \(RCC\\_PLLCFGR\)](#))

VCO output frequency = VCO input frequency × PLLI2SN with  $192 \leq \text{PLLI2SN} \leq 432$

00000000: PLLI2SN = 0, wrong configuration

00000001: PLLI2SN = 1, wrong configuration

...

01100000: PLLI2SN = 192

01100001: PLLI2SN = 193

01100010: PLLI2SN = 194

...

11011000: PLLI2SN = 432

11011000: PLLI2SN = 433, wrong configuration

...

11111111: PLLI2SN = 511, wrong configuration

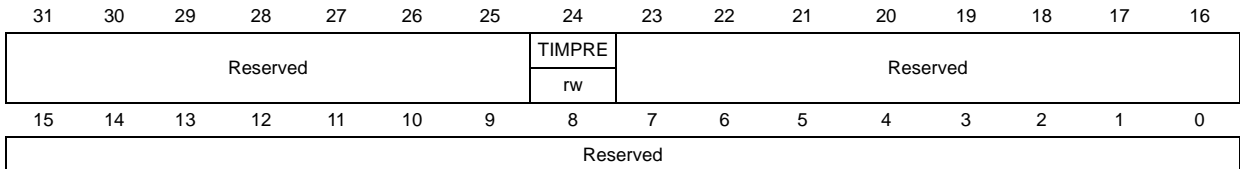
Bits 5:0 Reserved, must be kept at reset value.

### 6.3.21 RCC Dedicated Clocks Configuration Register (RCC\_DCKCFGR)

Address offset: 0x8C

Reset value: 0x0000 0000

Access: no wait state, word, half-word and byte access.



Bits 31:25 Reserved, must be kept at reset value.

Bit 24 **TIMPRE**: Timers clocks prescalers selection

Set and reset by software to control the clock frequency of all the timers connected to APB1 and APB2 domain.

0: If the APB prescaler (PPRE1, PPRE2 in the RCC\_CFGR register) is configured to a division factor of 1,  $TIMxCLK = HCLK$ . Otherwise, the timer clock frequencies are set to twice to the frequency of the APB domain to which the timers are connected:  
 $TIMxCLK = 2xPCLKx$ .

1: If the APB prescaler (PPRE1, PPRE2 in the RCC\_CFGR register) is configured to a division factor of 1 or 2,  $TIMxCLK = HCLK$ . Otherwise, the timer clock frequencies are set to four times to the frequency of the APB domain to which the timers are connected:  
 $TIMxCLK = 4xPCLKx$ .

Bits 23: 0 Reserved, must be kept at reset value.

### 6.3.22 RCC register map

Table 22 gives the register map and reset values

**Table 22. RCC register map and reset values for STM32F401xB/C and STM32F401xD/E**

Addr. offset	Register name	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
0x00	RCC_CR	Reserved				PLL12SRDY	PLL12SON	PLL12RDY	PLL12ON	Reserved				CSSON	HSEBYP	HSERDY	HSEON	HSICAL7	HSICAL6	HSICAL5	HSICAL4	HSICAL3	HSICAL2	HSICAL1	HSICAL0	HSITRIM4	HSITRIM3	HSITRIM2	HSITRIM1	HSITRIM0	Reserved	HSIRDY	HSION	
0x04	RCC_PLLCFGR	Reserved				PLLQ3	PLLQ2	PLLQ1	PLLQ0	Reserved	PLLSRC	Reserved				PLLP1	PLLP0	Reserved	PLLN8	PLLN7	PLLN6	PLLN5	PLLN4	PLLN3	PLLN2	PLLN1	PLLN0	PLLM5	PLLM4	PLLM3	PLLM2	PLLM1	PLLM0	
0x08	RCC_CFGR	MCO21	MCO20	MCO2PRE2	MCO2PRE1	MCO2PRE0	MCO1PRE2	MCO1PRE1	MCO1PRE0	I2SSRC	MCO11	MCO10	RTCPRE4	RTCPRE3	RTCPRE2	RTCPRE1	RTCPRE0	PPRE22	PPRE21	PPRE20	PPRE12	PPRE11	PPRE10	Reserved	Reserved	HPRE3	HPRE2	HPRE1	HPRE0	SWS1	SWS0	SW1	SW0	
0x0C	RCC_CIR	Reserved								CSSC	Reserved	PLL12SRDYC	PLL12DYC	HSERDYC	HSIRDYC	LSERDYC	LSIRDYC	Reserved	PLL12SRDYIE	PLL12DYIE	HSERDYIE	HSIRDYIE	LSERDYIE	LSIRDYIE	CSSF	Reserved	PLL12SRDYF	PLL12DYF	HSERDYF	HSIRDYF	LSERDYF	LSIRDYF		
0x10	RCC_AHB1RSTR	Reserved								DMA2RST	DMA1RST	Reserved						CRCRST	Reserved						GPIORST	Reserved	GPIORST	GPIODRST	GPIOCRST	GPIOBRST	GPIOARST			
0x14	RCC_AHB2RSTR	Reserved																OTGFSRST	Reserved															
0x18	Reserved	Reserved																																
0x1C	Reserved	Reserved																																
0x20	RCC_APB1RSTR	Reserved	PWRRST	Reserved				I2C3RST	I2C2RST	I2C1RST	Reserved				USART2RST	Reserved	SPI3RST	SPI2RST	Reserved	WWDGRST	Reserved										TIM5RST	TIM4RST	TIM3RST	TIM2RST
0x24	RCC_APB2RSTR	Reserved										TIM11RST	TIM10RST	TIM9RST	Reserved	SYSCFGGRST	SP45RST	SPI1RST	SDIORST	Reserved	ADC1RST	Reserved	USART6RST	USART1RST	Reserved	Reserved	TIM1RST							
0x28	Reserved	Reserved																																
0x2C	Reserved	Reserved																																
0x30	RCC_AHB1ENR	Reserved								DMA2EN	DMA1EN	Reserved						CRCCEN	Reserved						GPIOHEN	Reserved	GPIOEN	GPIODEN	GPIOCEN	GPIOBEN	GPIOAEN			
0x34	RCC_AHB2ENR	Reserved																OTGFSEN	Reserved															
0x38	Reserved	Reserved																																
0x3C	Reserved	Reserved																																



Table 22. RCC register map and reset values for STM32F401xB/C and STM32F401xD/E (continued)

Addr. offset	Register name	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0					
0x40	RCC_APB1ENR	Reserved		PWREN	Reserved					I2C3EN	I2C2EN	I2C1EN	Reserved		USART2EN	Reserved	SPI3EN	SPI2EN	Reserved		WWDGEN																	
0x44	RCC_APB2ENR	Reserved												TIM11EN	TIM10EN	TIM9EN	Reserved	SYSCFGEN	SPI4EN	SPI1EN	SPIOEN	Reserved	ADC1EN	Reserved	USART6EN	USART1EN		Reserved	TIM5EN	TIM4EN	TIM3EN	TIM2EN						
0x48	Reserved	Reserved																																				
0x4C	Reserved	Reserved																																				
0x50	RCC_AHB1LENR	Reserved										DMA2LPEN	DMA1LPEN	Reserved	SRAM1LPEN	FLITLPEN	Reserved	CRCLPEN	Reserved		GPIOLPEN	Reserved	GPIOLPEN	GPIODLPEN	GPIODLPEN	GPIODLPEN	GPIODLPEN	GPIODLPEN	GPIODLPEN	GPIODLPEN	GPIODLPEN	GPIODLPEN						
0x54	RCC_AHB2LENR	Reserved																							OTGFSLPEN	Reserved												
0x58	Reserved	Reserved																																				
0x5C	Reserved	Reserved																																				
0x60	RCC_APB1LENR	Reserved		PWRLPEN	Reserved					I2C3LPEN	I2C2LPEN	I2C1LPEN	Reserved		USART2LPEN	Reserved	SPI3LPEN	SPI2LPEN	Reserved		WWDGLPEN																	
0x64	RCC_APB2LENR	Reserved												TIM11LPEN	TIM10LPEN	TIM9LPEN	Reserved	SYSCFGLPEN	SPI4LPEN	SPI1LPEN	SDIOLPEN	Reserved	ADC1LPEN	Reserved	USART6LPEN	USART1LPEN		Reserved	TIM5LPEN	TIM4LPEN	TIM3LPEN	TIM2LPEN						
0x68	Reserved	Reserved																																				
0x6C	Reserved	Reserved																																				
0x70	RCC_BDCR	Reserved														BDRST	RTCEN	Reserved		RTCSEL1	RTCSEL0	Reserved																
0x74	RCC_CSR	LPWRRSTF	WWDGRSTF	WDGRSTF	SFTRSTF	PORRSTF	PADRSTF	BORRSTF	RMVF	Reserved																	LSIRDY	LSION										
0x78	Reserved	Reserved																																				
0x7C	Reserved	Reserved																																				
0x80	RCC_SSCGR	SSCGEN	SPREADSEL	Reserved	INCSTEP												MODPER																					
0x84	RCC_PLLI2S CFGR	Reserved	PLLI2SRx	Reserved												PLLI2SNx						Reserved																

**Table 22. RCC register map and reset values for STM32F401xB/C and STM32F401xD/E (continued)**

Addr. offset	Register name	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
0x88	Reserved																																	
0x8C	RCC_DCKCFGR	Reserved								TIMPRE	Reserved																							

Refer to [Table 1 on page 38](#) for the register boundary addresses.

## 7 System configuration controller (SYSCFG)

The system configuration controller is mainly used to remap the memory accessible in the code area and manage the external interrupt line connection to the GPIOs.

### 7.1 I/O compensation cell

By default the I/O compensation cell is not used. However when the I/O output buffer speed is configured in 50 MHz or 100 MHz mode, it is recommended to use the compensation cell for slew rate control on I/O  $t_{f(I/O)out}/t_{r(I/O)out}$  commutation to reduce the I/O noise on power supply.

When the compensation cell is enabled, a READY flag is set to indicate that the compensation cell is ready and can be used. The I/O compensation cell can be used only when the supply voltage ranges from 2.4 to 3.6 V.

### 7.2 SYSCFG registers

#### 7.2.1 SYSCFG memory remap register (SYSCFG\_MEMRMP)

This register is used for specific configurations on memory remap:

- Two bits are used to configure the type of memory accessible at address 0x0000 0000. These bits are used to select the physical remap by software and so, bypass the BOOT pins.
- After reset these bits take the value selected by the BOOT pins. When booting from main Flash memory with BOOT0 pin set to 0 this register takes the value 0x00.

In remap mode, the CPU can access the external memory via ICode bus instead of System bus which boosts up the performance.

Address offset: 0x00

Reset value: 0x0000 000X (X is the memory mode selected by the BOOT pins)

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved															
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved														MEM_MODE	
														rw	rw



Bits 31:2 Reserved, must be kept at reset value.

Bits 1:0 **MEM\_MODE**: Memory mapping selection

Set and cleared by software. This bit controls the memory internal mapping at address 0x0000 0000. After reset these bits take the value selected by the Boot pins .

00: Main Flash memory mapped at 0x0000 0000

01: System Flash memory mapped at 0x0000 0000

11: Embedded SRAM mapped at 0x0000 0000

*Note: Refer to [Section 2.3: Memory map](#) for details about the memory mapping at address 0x0000 0000.*

### 7.2.2 SYSCFG peripheral mode configuration register (SYSCFG\_PMC)

Address offset: 0x04

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved															ADC1D C2
															rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved															

Bits 31:17 Reserved, must be kept at reset value.

Bit 16 **ADCxDC2**:

0: No effect.

1: Refer to AN4073 on how to use this bit .

*Note: These bits can be set only if the following conditions are met:*

- ADC clock higher or equal to 30 MHz.

- Only one ADCxDC2 bit must be selected if ADC conversions do not start at the same time and the sampling times differ.

- These bits must not be set when the ADCDC1 bit is set in PWR\_CR register.

Bits 15:0 Reserved, must be kept at reset value.

### 7.2.3 SYSCFG external interrupt configuration register 1 (SYSCFG\_EXTICR1)

Address offset: 0x08

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved															
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
EXTI3[3:0]				EXTI2[3:0]				EXTI1[3:0]				EXTI0[3:0]			
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 31:16 Reserved, must be kept at reset value.

Bits 15:0 **EXTIx[3:0]**: EXTI x configuration (x = 0 to 3)

These bits are written by software to select the source input for the EXTIx external interrupt.

- 0000: PA[x] pin
- 0001: PB[x] pin
- 0010: PC[x] pin
- 0011: PD[x] pin
- 0100: PE[x] pin
- 0101: Reserved
- 0110: Reserved
- 0111: PH[x] pin

### 7.2.4 SYSCFG external interrupt configuration register 2 (SYSCFG\_EXTICR2)

Address offset: 0x0C

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved															
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
EXTI7[3:0]				EXTI6[3:0]				EXTI5[3:0]				EXTI4[3:0]			
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 31:16 Reserved, must be kept at reset value.

Bits 15:0 **EXTIx[3:0]**: EXTI x configuration (x = 4 to 7)

These bits are written by software to select the source input for the EXTIx external interrupt.

- 0000: PA[x] pin
- 0001: PB[x] pin
- 0010: PC[x] pin
- 0011: PD[x] pin
- 0100: PE[x] pin
- 0101: Reserved
- 0110: Reserved
- 0111: PH[x] pin

### 7.2.5 SYSCFG external interrupt configuration register 3 (SYSCFG\_EXTICR3)

Address offset: 0x10

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved															
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
EXTI11[3:0]				EXTI10[3:0]				EXTI9[3:0]				EXTI8[3:0]			
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 31:16 Reserved, must be kept at reset value.

Bits 15:0 **EXTIx[3:0]**: EXTI x configuration (x = 8 to 11)

These bits are written by software to select the source input for the EXTIx external interrupt.

- 0000: PA[x] pin
- 0001: PB[x] pin
- 0010: PC[x] pin
- 0011: PD[x] pin
- 0100: PE[x] pin
- 0101: Reserved
- 0110: Reserved
- 0111: PH[x] pin

### 7.2.6 SYSCFG external interrupt configuration register 4 (SYSCFG\_EXTICR4)

Address offset: 0x14

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved															
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
EXTI15[3:0]				EXTI14[3:0]				EXTI13[3:0]				EXTI12[3:0]			
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 31:16 Reserved, must be kept at reset value.

Bits 15:0 **EXTIx[3:0]**: EXTI x configuration (x = 12 to 15)

These bits are written by software to select the source input for the EXTIx external interrupt.

- 0000: PA[x] pin
- 0001: PB[x] pin
- 0010: PC[x] pin
- 0011: PD[x] pin
- 0100: PE[x] pin
- 0101: Reserved
- 0110: Reserved
- 0111: PH[x] pin

### 7.2.7 Compensation cell control register (SYSCFG\_CMPCR)

Address offset: 0x20

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved															
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved							READY	Reserved							CMP_PD
							r								rw

Bits 31:9 Reserved, must be kept at reset value.

Bit 8 **READY**: Compensation cell ready flag  
 0: I/O compensation cell not ready  
 1: O compensation cell ready

Bits 7:2 Reserved, must be kept at reset value.

Bit 0 **CMP\_PD**: Compensation cell power-down  
 0: I/O compensation cell power-down mode  
 1: I/O compensation cell enabled

### 7.2.8 SYSCFG register map

The following table gives the SYSCFG register map and the reset values.

**Table 23. SYSCFG register map and reset values**

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0x00	<b>SYSCFG_MEMRMP</b>	Reserved																										MEM_MODE					
	Reset value																											x x					
0x04	<b>SYSCFG_PMC</b>	Reserved														ADC1DC2	Reserved																
	Reset value															0																	
0x08	<b>SYSCFG_EXTICR1</b>	Reserved														EXTI3[3:0]			EXTI2[3:0]			EXTI1[3:0]			EXTI0[3:0]								
	Reset value															0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0		
0x0C	<b>SYSCFG_EXTICR2</b>	Reserved														EXTI7[3:0]			EXTI6[3:0]			EXTI5[3:0]			EXTI4[3:0]								
	Reset value															0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0		
0x10	<b>SYSCFG_EXTICR3</b>	Reserved														EXTI11[3:0]			EXTI10[3:0]			EXTI9[3:0]			EXTI8[3:0]								
	Reset value															0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0		
0x14	<b>SYSCFG_EXTICR4</b>	Reserved														EXTI15[3:0]			EXTI14[3:0]			EXTI13[3:0]			EXTI12[3:0]								
	Reset value															0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0		
0x20	<b>SYSCFG_CMPCR</b>	Reserved																								READY	Reserved			CMP_PD			
	Reset value																									0				0			

Refer to [Table 1 on page 38](#) for the register boundary addresses.

## 8 General-purpose I/Os (GPIO)

GPIO F/G/H/I/J/K (except GPIOH0 and GPIOH1) are not available in STM32F401xB/C and STM32F401xD/E.

### 8.1 GPIO introduction

Each general-purpose I/O port has four 32-bit configuration registers (GPIOx\_MODER, GPIOx\_OTYPER, GPIOx\_OSPEEDR and GPIOx\_PUPDR), two 32-bit data registers (GPIOx\_IDR and GPIOx\_ODR), a 32-bit set/reset register (GPIOx\_BSRR), a 32-bit locking register (GPIOx\_LCKR) and two 32-bit alternate function selection register (GPIOx\_AFRH and GPIOx\_AFRL).

### 8.2 GPIO main features

- Up to 16 I/Os under control
- Output states: push-pull or open drain + pull-up/down
- Output data from output data register (GPIOx\_ODR) or peripheral (alternate function output)
- Speed selection for each I/O
- Input states: floating, pull-up/down, analog
- Input data to input data register (GPIOx\_IDR) or peripheral (alternate function input)
- Bit set and reset register (GPIOx\_BSRR) for bitwise write access to GPIOx\_ODR
- Locking mechanism (GPIOx\_LCKR) provided to freeze the I/O configuration
- Analog function
- Alternate function input/output selection registers (at most 16 AFs per I/O)
- Fast toggle capable of changing every two clock cycles
- Highly flexible pin multiplexing allows the use of I/O pins as GPIOs or as one of several peripheral functions

### 8.3 GPIO functional description

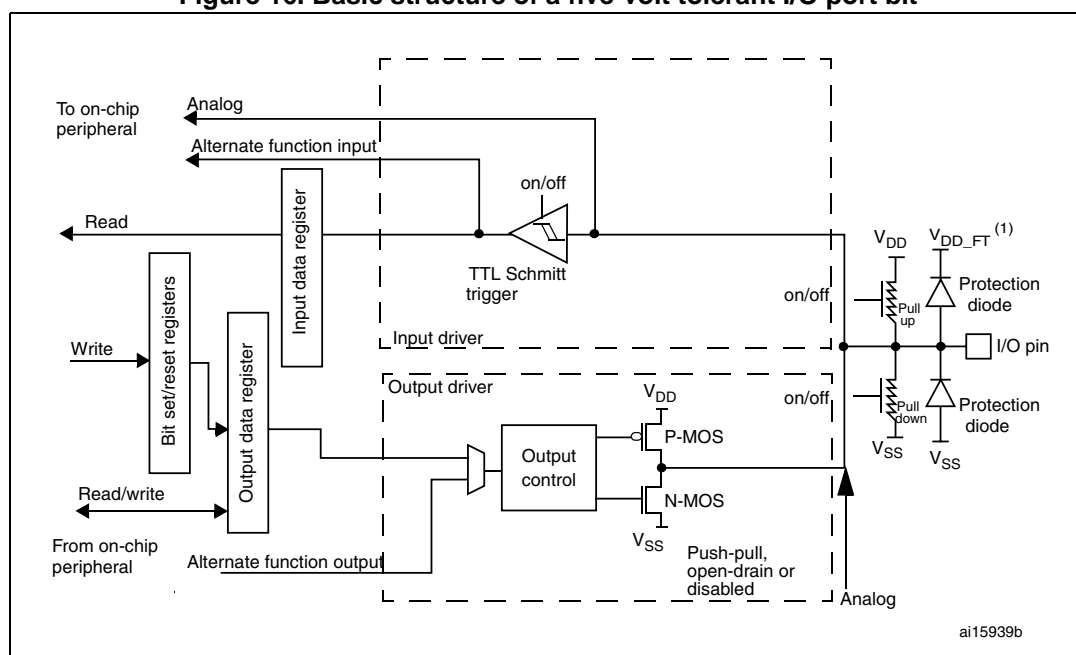
Subject to the specific hardware characteristics of each I/O port listed in the datasheet, each port bit of the general-purpose I/O (GPIO) ports can be individually configured by software in several modes:

- Input floating
- Input pull-up
- Input-pull-down
- Analog
- Output open-drain with pull-up or pull-down capability
- Output push-pull with pull-up or pull-down capability
- Alternate function push-pull with pull-up or pull-down capability
- Alternate function open-drain with pull-up or pull-down capability

Each I/O port bit is freely programmable, however the I/O port registers have to be accessed as 32-bit words, half-words or bytes. The purpose of the GPIOx\_BSRR register is to allow atomic read/modify accesses to any of the GPIO registers. In this way, there is no risk of an IRQ occurring between the read and the modify access.

show the basic structure of a 5 V tolerant I/O port bit. [Table 27](#) gives the possible port bit configurations.

**Figure 16. Basic structure of a five-volt tolerant I/O port bit**



1.  $V_{DD_{FT}}$  is a potential specific to five-volt tolerant I/Os and different from  $V_{DD}$ .

Table 24. Port bit configuration table<sup>(1)</sup>

MODER(i) [1:0]	OTYPER(i)	OSPEEDR(i) [B:A]		PUPDR(i) [1:0]		I/O configuration	
01	0	SPEED [B:A]		0	0	GP output	PP
	0			0	1	GP output	PP + PU
	0			1	0	GP output	PP + PD
	0			1	1	Reserved	
	1			0	0	GP output	OD
	1			0	1	GP output	OD + PU
	1			1	0	GP output	OD + PD
	1			1	Reserved (GP output OD)		
10	0	SPEED [B:A]		0	0	AF	PP
	0			0	1	AF	PP + PU
	0			1	0	AF	PP + PD
	0			1	1	Reserved	
	1			0	0	AF	OD
	1			0	1	AF	OD + PU
	1			1	0	AF	OD + PD
	1			1	Reserved		
00	x	x	x	0	0	Input	Floating
	x	x	x	0	1	Input	PU
	x	x	x	1	0	Input	PD
	x	x	x	1	1	Reserved (input floating)	
11	x	x	x	0	0	Input/output	Analog
	x	x	x	0	1	Reserved	
	x	x	x	1	0		
	x	x	x	1	1		

1. GP = general-purpose, PP = push-pull, PU = pull-up, PD = pull-down, OD = open-drain, AF = alternate function.



### 8.3.1 General-purpose I/O (GPIO)

During and just after reset, the alternate functions are not active and the I/O ports are configured in input floating mode.

The debug pins are in AF pull-up/pull-down after reset:

- PA15: JTDI in pull-up
- PA14: JTCK/SWCLK in pull-down
- PA13: JTMS/SWDAT in pull-up
- PB4: NJTRST in pull-up
- PB3: JTDO in floating state

When the pin is configured as output, the value written to the output data register (GPIOx\_ODR) is output on the I/O pin. It is possible to use the output driver in push-pull mode or open-drain mode (only the N-MOS is activated when 0 is output).

The input data register (GPIOx\_IDR) captures the data present on the I/O pin at every AHB clock cycle.

All GPIO pins have weak internal pull-up and pull-down resistors, which can be activated or not depending on the value in the GPIOx\_PUPDR register.

### 8.3.2 I/O pin multiplexer and mapping

The microcontroller I/O pins are connected to onboard peripherals/modules through a multiplexer that allows only one peripheral's alternate function (AF) connected to an I/O pin at a time. In this way, there can be no conflict between peripherals sharing the same I/O pin.

Each I/O pin has a multiplexer with sixteen alternate function inputs (AF0 to AF15) that can be configured through the GPIOx\_AFRL (for pin 0 to 7) and GPIOx\_AFRH (for pin 8 to 15) registers:

- After reset all I/Os are connected to the system's alternate function 0 (AF0)
- The peripherals' alternate functions are mapped from AF1 to AF13
- Cortex<sup>®</sup>-M4 with FPU EVENTOUT is mapped on AF15

This structure is shown in [Figure 17](#) below.

In addition to this flexible I/O multiplexing architecture, each peripheral has alternate functions mapped onto different I/O pins to optimize the number of peripherals available in smaller packages.

To use an I/O in a given configuration, proceed as follows:

- **System function**

Connect the I/O to AF0 and configure it depending on the function used:

- JTAG/SWD, after each device reset these pins are assigned as dedicated pins immediately usable by the debugger host (not controlled by the GPIO controller)
- RTC\_REFIN: this pin should be configured in Input floating mode
- MCO1 and MCO2: these pins have to be configured in alternate function mode.

*Note:* You can disable some or all of the JTAG/SWD pins and so release the associated pins for GPIO usage.

For more details please refer to [Section 6.2.10: Clock-out capability](#).

**Table 25. Flexible SWJ-DP pin assignment**

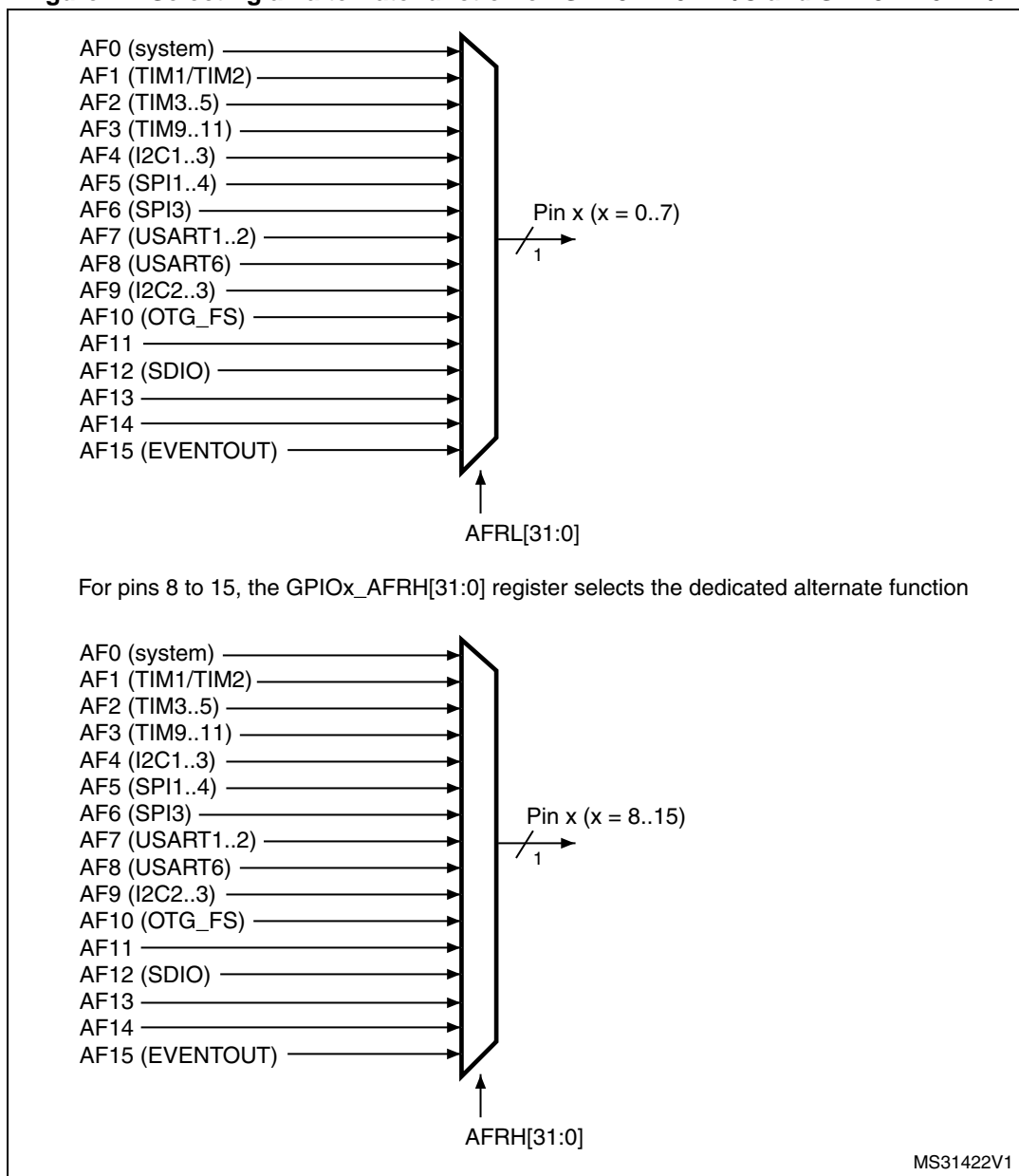
Available debug ports	SWJ I/O pin assigned				
	PA13 / JTMS / SWDIO	PA14 / JTCK / SWCLK	PA15 / JTDI	PB3 / JTDO	PB4 / NJTRST
Full SWJ (JTAG-DP + SW-DP) - Reset state	X	X	X	X	X
Full SWJ (JTAG-DP + SW-DP) but without NJTRST	X	X	X	X	
JTAG-DP Disabled and SW-DP Enabled	X	X			
JTAG-DP Disabled and SW-DP Disabled	Released				

- **GPIO**  
Configure the desired I/O as output or input in the GPIOx\_MODER register.
- **Peripheral alternate function**  
For the ADC, configure the desired I/O as analog in the GPIOx\_MODER register.  
For other peripherals:
  - Configure the desired I/O as an alternate function in the GPIOx\_MODER register
  - Select the type, pull-up/pull-down and output speed via the GPIOx\_OTYPER, GPIOx\_PUPDR and GPIOx\_OSPEEDER registers, respectively
  - Connect the I/O to the desired AFx in the GPIOx\_AFRL or GPIOx\_AFRH register
- **EVENTOUT**  
Configure the I/O pin used to output the Cortex<sup>®</sup>-M4 with FPU EVENTOUT signal by connecting it to AF15

*Note:* *EVENTOUT is not mapped onto the following I/O pins: PC13, PC14, PC15, PH0 and PH1.*

Please refer to the “Alternate function mapping” table in the datasheets for the detailed mapping of the system and peripherals’ alternate function I/O pins.

Figure 17. Selecting an alternate function on STM32F401xB/C and STM32F401xD/E



1. Configured in FS.

### 8.3.3 I/O port control registers

Each of the GPIOs has four 32-bit memory-mapped control registers (GPIOx\_MODER, GPIOx\_OTYPER, GPIOx\_OSPEEDR, GPIOx\_PUPDR) to configure up to 16 I/Os.

The GPIOx\_MODER register is used to select the I/O direction (input, output, AF, analog). The GPIOx\_OTYPER and GPIOx\_OSPEEDR registers are used to select the output type (push-pull or open-drain) and speed (the I/O speed pins are directly connected to the corresponding GPIOx\_OSPEEDR register bits whatever the I/O direction). The GPIOx\_PUPDR register is used to select the pull-up/pull-down whatever the I/O direction.

### 8.3.4 I/O port data registers

Each GPIO has two 16-bit memory-mapped data registers: input and output data registers (GPIOx\_IDR and GPIOx\_ODR). GPIOx\_ODR stores the data to be output, it is read/write accessible. The data input through the I/O are stored into the input data register (GPIOx\_IDR), a read-only register.

See [Section 8.4.5: GPIO port input data register \(GPIOx\\_IDR\) \(x = A..E and H\)](#) and [Section 8.4.6: GPIO port output data register \(GPIOx\\_ODR\) \(x = A..E and H\)](#) for the register descriptions.

### 8.3.5 I/O data bitwise handling

The bit set reset register (GPIOx\_BSRR) is a 32-bit register which allows the application to set and reset each individual bit in the output data register (GPIOx\_ODR). The bit set reset register has twice the size of GPIOx\_ODR.

To each bit in GPIOx\_ODR, correspond two control bits in GPIOx\_BSRR: BSRR(i) and BSRR(i+SIZE). When written to 1, bit BSRR(i) sets the corresponding ODR(i) bit. When written to 1, bit BSRR(i+SIZE) resets the ODR(i) corresponding bit.

Writing any bit to 0 in GPIOx\_BSRR does not have any effect on the corresponding bit in GPIOx\_ODR. If there is an attempt to both set and reset a bit in GPIOx\_BSRR, the set action takes priority.

Using the GPIOx\_BSRR register to change the values of individual bits in GPIOx\_ODR is a “one-shot” effect that does not lock the GPIOx\_ODR bits. The GPIOx\_ODR bits can always be accessed directly. The GPIOx\_BSRR register provides a way of performing atomic bitwise handling.

There is no need for the software to disable interrupts when programming the GPIOx\_ODR at bit level: it is possible to modify one or more bits in a single atomic AHB1 write access.

### 8.3.6 GPIO locking mechanism

It is possible to freeze the GPIO control registers by applying a specific write sequence to the GPIOx\_LCKR register. The frozen registers are GPIOx\_MODER, GPIOx\_OTYPER, GPIOx\_OSPEEDR, GPIOx\_PUPDR, GPIOx\_AFRL and GPIOx\_AFRH.

To write the GPIOx\_LCKR register, a specific write / read sequence has to be applied. When the right LOCK sequence is applied to bit 16 in this register, the value of LCKR[15:0] is used to lock the configuration of the I/Os (during the write sequence the LCKR[15:0] value must be the same). When the LOCK sequence has been applied to a port bit, the value of the port bit can no longer be modified until the next MCU or peripheral reset. Each GPIOx\_LCKR bit freezes the corresponding bit in the control registers (GPIOx\_MODER, GPIOx\_OTYPER, GPIOx\_OSPEEDR, GPIOx\_PUPDR, GPIOx\_AFRL and GPIOx\_AFRH).

The LOCK sequence (refer to [Section 8.4.8: GPIO port configuration lock register \(GPIOx\\_LCKR\) \(x = A..E and H\)](#)) can only be performed using a word (32-bit long) access to the GPIOx\_LCKR register due to the fact that GPIOx\_LCKR bit 16 has to be set at the same time as the [15:0] bits.

For more details please refer to LCKR register description in [Section 8.4.8: GPIO port configuration lock register \(GPIOx\\_LCKR\) \(x = A..E and H\)](#).

### 8.3.7 I/O alternate function input/output

Two registers are provided to select one out of the sixteen alternate function inputs/outputs available for each I/O. With these registers, you can connect an alternate function to some other pin as required by your application.

This means that a number of possible peripheral functions are multiplexed on each GPIO using the GPIOx\_AFRL and GPIOx\_AFRH alternate function registers. The application can thus select any one of the possible functions for each I/O. The AF selection signal being common to the alternate function input and alternate function output, a single channel is selected for the alternate function input/output of one I/O.

To know which functions are multiplexed on each GPIO pin, refer to the datasheets.

*Note: The application is allowed to select one of the possible peripheral functions for each I/O at a time.*

### 8.3.8 External interrupt/wakeup lines

All ports have external interrupt capability. To use external interrupt lines, the port must be configured in input mode, refer to [Section 10.2: External interrupt/event controller \(EXTI\)](#) and [Section 10.2.3: Wakeup event management](#).

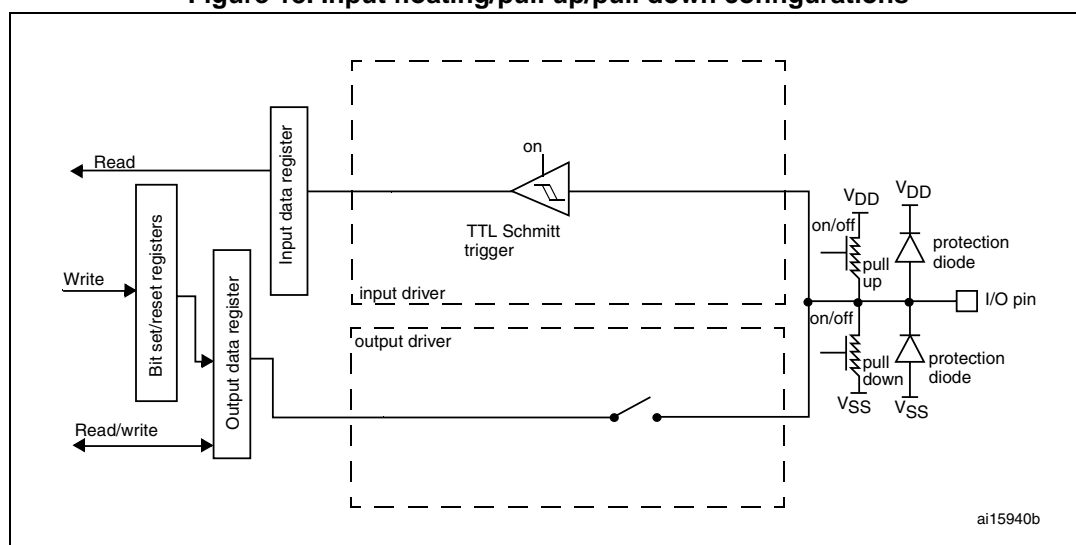
### 8.3.9 Input configuration

When the I/O port is programmed as Input:

- the output buffer is disabled
- the Schmitt trigger input is activated
- the pull-up and pull-down resistors are activated depending on the value in the GPIOx\_PUPDR register
- The data present on the I/O pin are sampled into the input data register every AHB clock cycle
- A read access to the input data register provides the I/O State

Figure 18 shows the input configuration of the I/O port bit.

Figure 18. Input floating/pull up/pull down configurations

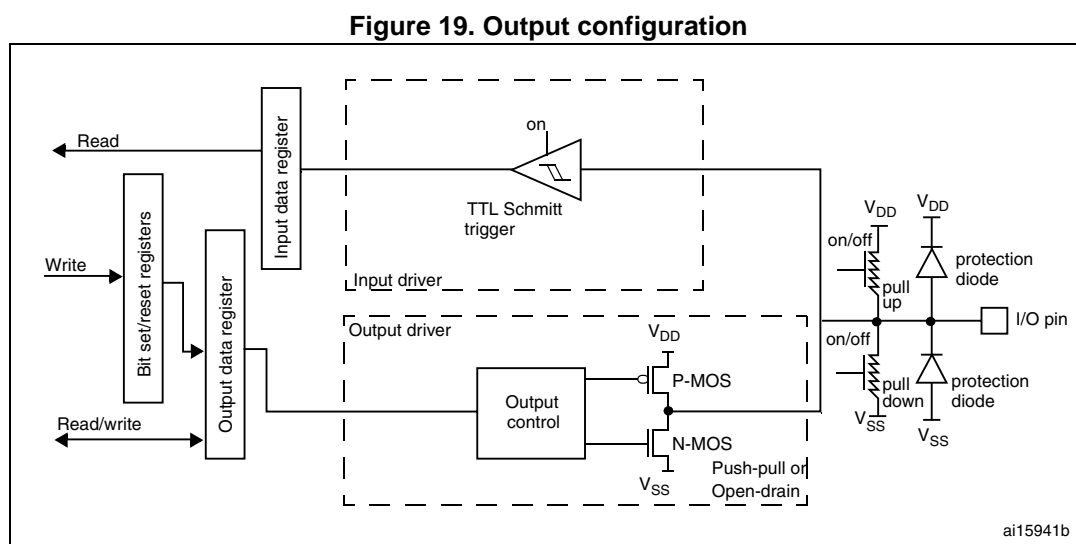


### 8.3.10 Output configuration

When the I/O port is programmed as output:

- The output buffer is enabled:
  - Open drain mode: A “0” in the Output register activates the N-MOS whereas a “1” in the Output register leaves the port in Hi-Z (the P-MOS is never activated)
  - Push-pull mode: A “0” in the Output register activates the N-MOS whereas a “1” in the Output register activates the P-MOS
- The Schmitt trigger input is activated
- The weak pull-up and pull-down resistors are activated or not depending on the value in the GPIOx\_PUPDR register
- The data present on the I/O pin are sampled into the input data register every AHB clock cycle
- A read access to the input data register gets the I/O state
- A read access to the output data register gets the last written value

Figure 19 shows the output configuration of the I/O port bit.



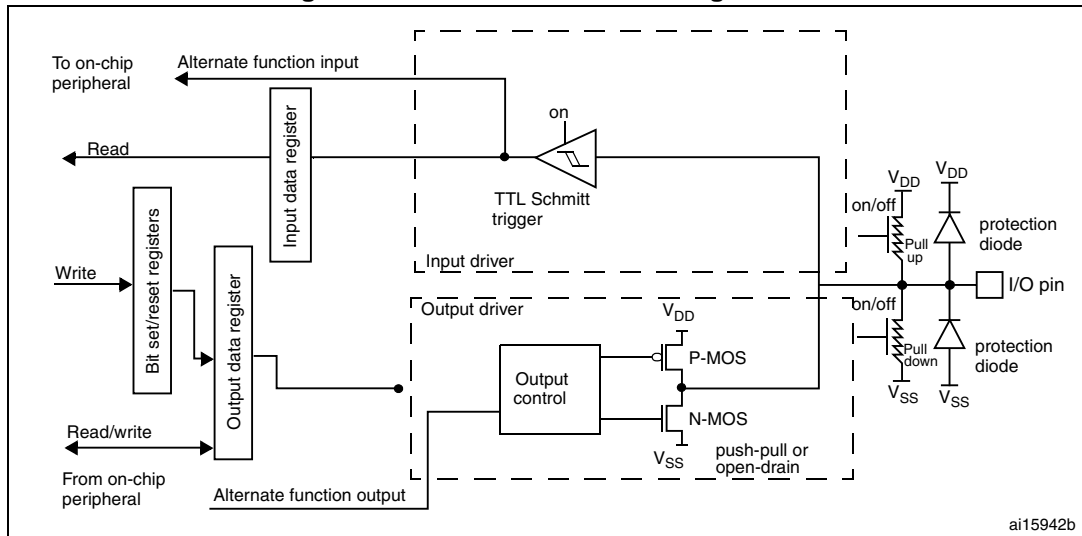
### 8.3.11 Alternate function configuration

When the I/O port is programmed as alternate function:

- The output buffer can be configured as open-drain or push-pull
- The output buffer is driven by the signal coming from the peripheral (transmitter enable and data)
- The Schmitt trigger input is activated
- The weak pull-up and pull-down resistors are activated or not depending on the value in the GPIOx\_PUPDR register
- The data present on the I/O pin are sampled into the input data register every AHB clock cycle
- A read access to the input data register gets the I/O state

Figure 20 shows the Alternate function configuration of the I/O port bit.

Figure 20. Alternate function configuration



### 8.3.12 Analog configuration

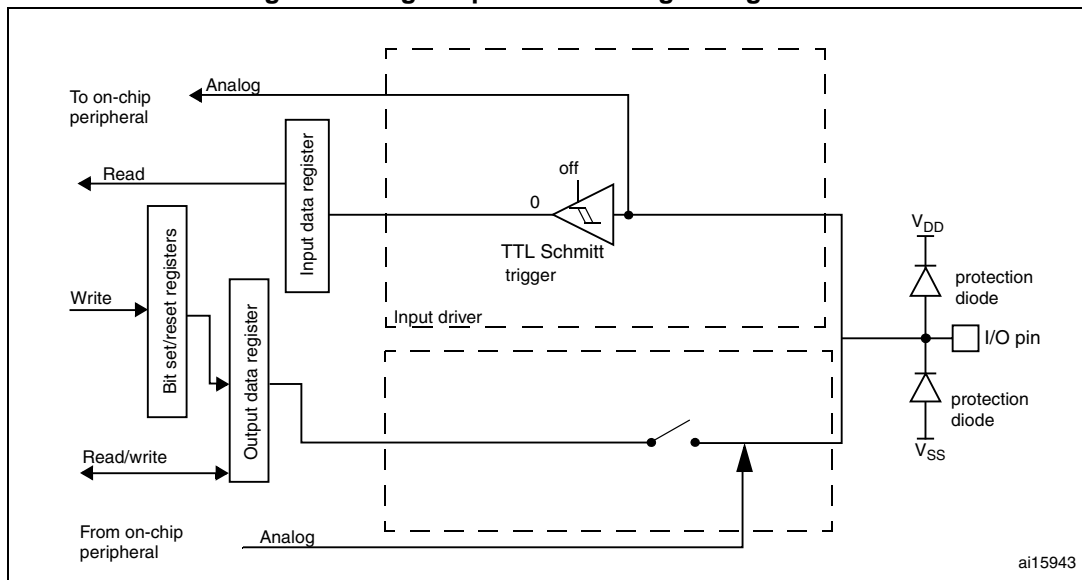
When the I/O port is programmed as analog configuration:

- The output buffer is disabled
- The Schmitt trigger input is deactivated, providing zero consumption for every analog value of the I/O pin. The output of the Schmitt trigger is forced to a constant value (0).
- The weak pull-up and pull-down resistors are disabled
- Read access to the input data register gets the value “0”

Note: In the analog configuration, the I/O pins cannot be 5 Volt tolerant.

Figure 21 shows the high-impedance, analog-input configuration of the I/O port bit.

Figure 21. High impedance-analog configuration



### 8.3.13 Using the OSC32\_IN/OSC32\_OUT pins as GPIO PC14/PC15 port pins

The LSE oscillator pins OSC32\_IN and OSC32\_OUT can be used as general-purpose PC14 and PC15 I/Os, respectively, when the LSE oscillator is off. The PC14 and PC15 I/Os are only configured as LSE oscillator pins OSC32\_IN and OSC32\_OUT when the LSE oscillator is ON. This is done by setting the LSEON bit in the RCC\_BDCR register. The LSE has priority over the GPIO function.

*Note:* The PC14/PC15 GPIO functionality is lost when the 1.2 V domain is powered off (by the device entering the standby mode) or when the backup domain is supplied by V<sub>BAT</sub> (V<sub>DD</sub> no more supplied). In this case the I/Os are set in analog input mode.

### 8.3.14 Using the OSC\_IN/OSC\_OUT pins as GPIO PH0/PH1 port pins

The HSE oscillator pins OSC\_IN/OSC\_OUT can be used as general-purpose PH0/PH1 I/Os, respectively, when the HSE oscillator is OFF. (after reset, the HSE oscillator is off). The PH0/PH1 I/Os are only configured as OSC\_IN/OSC\_OUT HSE oscillator pins when the HSE oscillator is ON. This is done by setting the HSEON bit in the RCC\_CR register. The HSE has priority over the GPIO function.

### 8.3.15 Selection of RTC functions

The STM32F4xx feature one GPIO pins RTC\_AF1 that can be used for the detection of a tamper or time stamp event, or RTC\_ALARM, or RTC\_CALIB RTC outputs.

- The RTC\_AF1 (PC13) can be used for the following purposes:

RTC\_ALARM output: this output can be RTC Alarm A, RTC Alarm B or RTC Wakeup depending on the OSEL[1:0] bits in the RTC\_CR register

- RTC\_CALIB output: this feature is enabled by setting the COE[23] in the RTC\_CR register
- RTC\_TAMP1: tamper event detection
- RTC\_TS: time stamp event detection

The selection of the corresponding pin is performed through the RTC\_TAFCR register as follows:

- TAMP1INSEL is used to select which pin is used as the RTC\_TAMP1 tamper input
- TSINSEL is used to select which pin is used as the RTC\_TS time stamp input
- ALARMOUTTYPE is used to select whether the RTC\_ALARM is output in push-pull or open-drain mode

The output mechanism follows the priority order listed in [Table 26](#).



Table 26. RTC additional functions<sup>(1)</sup>

Pin configuration and function	RTC_ALARM enabled	RTC_CALIB enabled	Tamper enabled	Time stamp enabled	TAMP1INSEL TAMPER1 pin selection	TSINSEL TIMESTAMP pin selection	ALARMOUTTYPE RTC_ALARM configuration
Alarm out output OD	1	Don't care	Don't care	Don't care	Don't care	Don't care	0
Alarm out output PP	1	Don't care	Don't care	Don't care	Don't care	Don't care	1
Calibration out output PP	0	1	Don't care	Don't care	Don't care	Don't care	Don't care
TAMPER1 input floating	0	0	1	0	0	Don't care	Don't care
TIMESTAMP and TAMPER1 input floating	0	0	1	1	0	0	Don't care
TIMESTAMP input floating	0	0	0	1	Don't care	0	Don't care
Standard GPIO	0	0	0	0	Don't care	Don't care	Don't care

1. OD: open drain; PP: push-pull.

## 8.4 GPIO registers

This section gives a detailed description of the GPIO registers.

For a summary of register bits, register address offsets and reset values, refer to [Table 27](#).

The GPIO registers can be accessed by byte (8 bits), half-words (16 bits) or words (32 bits).

### 8.4.1 GPIO port mode register (GPIOx\_MODER) (x = A..E and H)

Address offset: 0x00

Reset values:

- 0x0C00 0000 for port A
- 0x0000 0280 for port B
- 0x0000 0000 for other ports

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
MODER15[1:0]		MODER14[1:0]		MODER13[1:0]		MODER12[1:0]		MODER11[1:0]		MODER10[1:0]		MODER9[1:0]		MODER8[1:0]	
r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
MODER7[1:0]		MODER6[1:0]		MODER5[1:0]		MODER4[1:0]		MODER3[1:0]		MODER2[1:0]		MODER1[1:0]		MODER0[1:0]	
r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w

Bits 2y:2y+1 **MODERy[1:0]**: Port x configuration bits (y = 0..15)

These bits are written by software to configure the I/O direction mode.

00: Input (reset state)

01: General purpose output mode

10: Alternate function mode

11: Analog mode

### 8.4.2 GPIO port output type register (GPIOx\_OTYPER) (x = A..E and H)

Address offset: 0x04

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved															
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
OT15	OT14	OT13	OT12	OT11	OT10	OT9	OT8	OT7	OT6	OT5	OT4	OT3	OT2	OT1	OT0
r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w

Bits 31:16 Reserved, must be kept at reset value.

Bits 15:0 **OTy**: Port x configuration bits (y = 0..15)

These bits are written by software to configure the output type of the I/O port.

0: Output push-pull (reset state)

1: Output open-drain

### 8.4.3 GPIO port output speed register (GPIOx\_OSPEEDR) (x = A..E and H)

Address offset: 0x08

Reset values:

- 0x0C00 0000 for port A
- 0x0000 00C0 for port B
- 0x0000 0000 for other ports

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
OSPEEDR15 [1:0]		OSPEEDR14 [1:0]		OSPEEDR13 [1:0]		OSPEEDR12 [1:0]		OSPEEDR11 [1:0]		OSPEEDR10 [1:0]		OSPEEDR9 [1:0]		OSPEEDR8 [1:0]	
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
OSPEEDR7[1:0]		OSPEEDR6[1:0]		OSPEEDR5[1:0]		OSPEEDR4[1:0]		OSPEEDR3[1:0]		OSPEEDR2[1:0]		OSPEEDR1 [1:0]		OSPEEDR0 [1:0]	
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 2y:2y+1 **OSPEEDRy[1:0]**: Port x configuration bits (y = 0..15)

These bits are written by software to configure the I/O output speed.

- 00: Low speed
- 01: Medium speed
- 10: Fast speed
- 11: High speed

*Note: Refer to the product datasheets for the values of OSPEEDRy bits versus V<sub>DD</sub> range and external load.*

### 8.4.4 GPIO port pull-up/pull-down register (GPIOx\_PUPDR) (x = A..E and H)

Address offset: 0x0C

Reset values:

- 0x6400 0000 for port A
- 0x0000 0100 for port B
- 0x0000 0000 for other ports

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
PUPDR15[1:0]		PUPDR14[1:0]		PUPDR13[1:0]		PUPDR12[1:0]		PUPDR11[1:0]		PUPDR10[1:0]		PUPDR9[1:0]		PUPDR8[1:0]	
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
PUPDR7[1:0]		PUPDR6[1:0]		PUPDR5[1:0]		PUPDR4[1:0]		PUPDR3[1:0]		PUPDR2[1:0]		PUPDR1[1:0]		PUPDR0[1:0]	
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 2y:2y+1 **PUPDRy[1:0]**: Port x configuration bits (y = 0..15)

These bits are written by software to configure the I/O pull-up or pull-down

00: No pull-up, pull-down

01: Pull-up

10: Pull-down

11: Reserved

### 8.4.5 GPIO port input data register (GPIOx\_IDR) (x = A..E and H)

Address offset: 0x10

Reset value: 0x0000 XXXX (where X means undefined)

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved															
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
IDR15	IDR14	IDR13	IDR12	IDR11	IDR10	IDR9	IDR8	IDR7	IDR6	IDR5	IDR4	IDR3	IDR2	IDR1	IDR0
r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r

Bits 31:16 Reserved, must be kept at reset value.

Bits 15:0 **IDRy**: Port input data (y = 0..15)

These bits are read-only and can be accessed in word mode only. They contain the input value of the corresponding I/O port.

### 8.4.6 GPIO port output data register (GPIOx\_ODR) (x = A..E and H)

Address offset: 0x14

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved															
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
ODR15	ODR14	ODR13	ODR12	ODR11	ODR10	ODR9	ODR8	ODR7	ODR6	ODR5	ODR4	ODR3	ODR2	ODR1	ODR0
r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w

Bits 31:16 Reserved, must be kept at reset value.

Bits 15:0 **ODRy**: Port output data (y = 0..15)

These bits can be read and written by software.

*Note: For atomic bit set/reset, the ODR bits can be individually set and reset by writing to the GPIOx\_BSRR register (x = A..E and H).*

### 8.4.7 GPIO port bit set/reset register (GPIOx\_BSRR) (x = A..E and H)

Address offset: 0x18

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
BR15	BR14	BR13	BR12	BR11	BR10	BR9	BR8	BR7	BR6	BR5	BR4	BR3	BR2	BR1	BR0
w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
BS15	BS14	BS13	BS12	BS11	BS10	BS9	BS8	BS7	BS6	BS5	BS4	BS3	BS2	BS1	BS0
w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w

Bits 31:16 **BRy**: Port x reset bit y (y = 0..15)

These bits are write-only and can be accessed in word, half-word or byte mode. A read to these bits returns the value 0x0000.

- 0: No action on the corresponding ODRx bit
- 1: Resets the corresponding ODRx bit

*Note: If both BSx and BRx are set, BSx has priority.*

Bits 15:0 **BSy**: Port x set bit y (y= 0..15)

These bits are write-only and can be accessed in word, half-word or byte mode. A read to these bits returns the value 0x0000.

- 0: No action on the corresponding ODRx bit
- 1: Sets the corresponding ODRx bit

### 8.4.8 GPIO port configuration lock register (GPIOx\_LCKR) (x = A..E and H)

This register is used to lock the configuration of the port bits when a correct write sequence is applied to bit 16 (LCKK). The value of bits [15:0] is used to lock the configuration of the GPIO. During the write sequence, the value of LCKR[15:0] must not change. When the LOCK sequence has been applied on a port bit, the value of this port bit can no longer be modified until the next MCU or peripheral reset.

*Note: A specific write sequence is used to write to the GPIOx\_LCKR register. Only word access (32-bit long) is allowed during this write sequence.*

Each lock bit freezes a specific configuration register (control and alternate function registers).

Address offset: 0x1C

Reset value: 0x0000 0000

Access: 32-bit word only, read/write register

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved															LCKK
															r/w
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
LCK15	LCK14	LCK13	LCK12	LCK11	LCK10	LCK9	LCK8	LCK7	LCK6	LCK5	LCK4	LCK3	LCK2	LCK1	LCK0
r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w



Bits 31:17 Reserved, must be kept at reset value.

Bit 16 **LCKK[16]**: Lock key

This bit can be read any time. It can only be modified using the lock key write sequence.

0: Port configuration lock key not active

1: Port configuration lock key active. The GPIOx\_LCKR register is locked until an MCU reset or a peripheral reset occurs.

LOCK key write sequence:

WR LCKR[16] = '1' + LCKR[15:0]

WR LCKR[16] = '0' + LCKR[15:0]

WR LCKR[16] = '1' + LCKR[15:0]

RD LCKR

RD LCKR[16] = '1' (this read operation is optional but it confirms that the lock is active)

*Note: During the LOCK key write sequence, the value of LCK[15:0] must not change.*

*Any error in the lock sequence aborts the lock.*

*After the first lock sequence on any bit of the port, any read access on the LCKK bit will return '1' until the next CPU reset.*

Bits 15:0 **LCKy**: Port x lock bit y (y= 0..15)

These bits are read/write but can only be written when the LCKK bit is '0'.

0: Port configuration not locked

1: Port configuration locked

### 8.4.9 GPIO alternate function low register (GPIOx\_AFRL) (x = A..E and H)

Address offset: 0x20

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
AFRL7[3:0]				AFRL6[3:0]				AFRL5[3:0]				AFRL4[3:0]			
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
AFRL3[3:0]				AFRL2[3:0]				AFRL1[3:0]				AFRL0[3:0]			
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 31:0 **AFRLy**: Alternate function selection for port x bit y (y = 0..7)

These bits are written by software to configure alternate function I/Os

AFRLy selection:

0000: AF0	1000: AF8
0001: AF1	1001: AF9
0010: AF2	1010: AF10
0011: AF3	1011: AF11
0100: AF4	1100: AF12
0101: AF5	1101: AF13
0110: AF6	1110: AF14
0111: AF7	1111: AF15

### 8.4.10 GPIO alternate function high register (GPIOx\_AFRH) (x = A..E and H)

Address offset: 0x24

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
AFRH15[3:0]				AFRH14[3:0]				AFRH13[3:0]				AFRH12[3:0]			
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
AFRH11[3:0]				AFRH10[3:0]				AFRH9[3:0]				AFRH8[3:0]			
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 31:0 **AFRHy**: Alternate function selection for port x bit y (y = 8..15)

These bits are written by software to configure alternate function I/Os

AFRHy selection:

0000: AF0	1000: AF8
0001: AF1	1001: AF9
0010: AF2	1010: AF10
0011: AF3	1011: AF11
0100: AF4	1100: AF12
0101: AF5	1101: AF13
0110: AF6	1110: AF14
0111: AF7	1111: AF15

### 8.4.11 GPIO register map

The following table gives the GPIO register map and the reset values.

Table 27. GPIO register map and reset values

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0x00	<b>GPIOA_MODER</b>	MODER15[1:0]	MODER14[1:0]	MODER13[1:0]	MODER12[1:0]	MODER11[1:0]	MODER10[1:0]	MODER9[1:0]	MODER8[1:0]	MODER7[1:0]	MODER6[1:0]	MODER5[1:0]	MODER4[1:0]	MODER3[1:0]	MODER2[1:0]	MODER1[1:0]	MODER0[1:0]																
	Reset value	0	0	0	0	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	
0x00	<b>GPIOB_MODER</b>	MODER15[1:0]	MODER14[1:0]	MODER13[1:0]	MODER12[1:0]	MODER11[1:0]	MODER10[1:0]	MODER9[1:0]	MODER8[1:0]	MODER7[1:0]	MODER6[1:0]	MODER5[1:0]	MODER4[1:0]	MODER3[1:0]	MODER2[1:0]	MODER1[1:0]	MODER0[1:0]																
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0
0x00	<b>GPIOx_MODER</b> (where x = C..E and H)	MODER15[1:0]	MODER14[1:0]	MODER13[1:0]	MODER12[1:0]	MODER11[1:0]	MODER10[1:0]	MODER9[1:0]	MODER8[1:0]	MODER7[1:0]	MODER6[1:0]	MODER5[1:0]	MODER4[1:0]	MODER3[1:0]	MODER2[1:0]	MODER1[1:0]	MODER0[1:0]																
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0



Table 27. GPIO register map and reset values (continued)

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0		
0x04	GPIOx_OTYPER (where x = A..E and H)	Reserved																OT15	OT14	OT13	OT12	OT11	OT10	OT9	OT8	OT7	OT6	OT5	OT4	OT3	OT2	OT1	OT0		
	Reset value																	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x08	GPIOx_OSPEEDER (where x = C..E and H)	OSPEEDR15[1:0]		OSPEEDR14[1:0]		OSPEEDR13[1:0]		OSPEEDR12[1:0]		OSPEEDR11[1:0]		OSPEEDR10[1:0]		OSPEEDR9[1:0]		OSPEEDR8[1:0]		OSPEEDR7[1:0]		OSPEEDR6[1:0]		OSPEEDR5[1:0]		OSPEEDR4[1:0]		OSPEEDR3[1:0]		OSPEEDR2[1:0]		OSPEEDR1[1:0]		OSPEEDR0[1:0]			
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0		
0x08	GPIOA_OSPEEDER	OSPEEDR15[1:0]		OSPEEDR14[1:0]		OSPEEDR13[1:0]		OSPEEDR12[1:0]		OSPEEDR11[1:0]		OSPEEDR10[1:0]		OSPEEDR9[1:0]		OSPEEDR8[1:0]		OSPEEDR7[1:0]		OSPEEDR6[1:0]		OSPEEDR5[1:0]		OSPEEDR4[1:0]		OSPEEDR3[1:0]		OSPEEDR2[1:0]		OSPEEDR1[1:0]		OSPEEDR0[1:0]			
	Reset value	0	0	0	0	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0		
0x08	GPIOB_OSPEEDER	OSPEEDR15[1:0]		OSPEEDR14[1:0]		OSPEEDR13[1:0]		OSPEEDR12[1:0]		OSPEEDR11[1:0]		OSPEEDR10[1:0]		OSPEEDR9[1:0]		OSPEEDR8[1:0]		OSPEEDR7[1:0]		OSPEEDR6[1:0]		OSPEEDR5[1:0]		OSPEEDR4[1:0]		OSPEEDR3[1:0]		OSPEEDR2[1:0]		OSPEEDR1[1:0]		OSPEEDR0[1:0]			
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	0	0	0	0	0	0		
0x0C	GPIOA_PUPDR	PUPDR15[1:0]		PUPDR14[1:0]		PUPDR13[1:0]		PUPDR12[1:0]		PUPDR11[1:0]		PUPDR10[1:0]		PUPDR9[1:0]		PUPDR8[1:0]		PUPDR7[1:0]		PUPDR6[1:0]		PUPDR5[1:0]		PUPDR4[1:0]		PUPDR3[1:0]		PUPDR2[1:0]		PUPDR1[1:0]		PUPDR0[1:0]			
	Reset value	0	1	1	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0		
0x0C	GPIOB_PUPDR	PUPDR15[1:0]		PUPDR14[1:0]		PUPDR13[1:0]		PUPDR12[1:0]		PUPDR11[1:0]		PUPDR10[1:0]		PUPDR9[1:0]		PUPDR8[1:0]		PUPDR7[1:0]		PUPDR6[1:0]		PUPDR5[1:0]		PUPDR4[1:0]		PUPDR3[1:0]		PUPDR2[1:0]		PUPDR1[1:0]		PUPDR0[1:0]			
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0		
0x0C	GPIOx_PUPDR (where x = C..E and H)	PUPDR15[1:0]		PUPDR14[1:0]		PUPDR13[1:0]		PUPDR12[1:0]		PUPDR11[1:0]		PUPDR10[1:0]		PUPDR9[1:0]		PUPDR8[1:0]		PUPDR7[1:0]		PUPDR6[1:0]		PUPDR5[1:0]		PUPDR4[1:0]		PUPDR3[1:0]		PUPDR2[1:0]		PUPDR1[1:0]		PUPDR0[1:0]			
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0		
0x10	GPIOx_IDR (where x = A..E and H)	Reserved																IDR15	IDR14	IDR13	IDR12	IDR11	IDR10	IDR9	IDR8	IDR7	IDR6	IDR5	IDR4	IDR3	IDR2	IDR1	IDR0		
	Reset value																	x	x	x	x	x	x	x	x	x	x	x	x	x	x	x	x	x	
0x14	GPIOx_ODR (where x = A..E and H)	Reserved																ODR15	ODR14	ODR13	ODR12	ODR11	ODR10	ODR9	ODR8	ODR7	ODR6	ODR5	ODR4	ODR3	ODR2	ODR1	ODR0		
	Reset value																	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	
0x18	GPIOx_BSRR (where x = A..E and H)	BR15	BR14	BR13	BR12	BR11	BR10	BR9	BR8	BR7	BR6	BR5	BR4	BR3	BR2	BR1	BR0	BS15	BS14	BS13	BS12	BS11	BS10	BS9	BS8	BS7	BS6	BS5	BS4	BS3	BS2	BS1	BS0		
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0		





Table 27. GPIO register map and reset values (continued)

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0			
0x1C	GPIOx_LCKR (where x = A..E and H)	Reserved															LCKK	LCK15	LCK14	LCK13	LCK12	LCK11	LCK10	LCK9	LCK8	LCK7	LCK6	LCK5	LCK4	LCK3	LCK2	LCK1	LCK0			
	Reset value																0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	
0x20	GPIOx_AFRL (where x = A..E and H)	AFRL7[3:0]				AFRL6[3:0]				AFRL5[3:0]				AFRL4[3:0]				AFRL3[3:0]				AFRL2[3:0]				AFRL1[3:0]				AFRL0[3:0]						
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x24	GPIOx_AFRH (where x = A..E and H)	AFRH15[3:0]				AFRH14[3:0]				AFRH13[3:0]				AFRH12[3:0]				AFRH11[3:0]				AFRH10[3:0]				AFRH9[3:0]				AFRH8[3:0]						
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Refer to [Table 1 on page 38](#) for the register boundary addresses.

## 9 DMA controller (DMA)

### 9.1 DMA introduction

Direct memory access (DMA) is used in order to provide high-speed data transfer between peripherals and memory and between memory and memory. Data can be quickly moved by DMA without any CPU action. This keeps CPU resources free for other operations.

The DMA controller combines a powerful dual AHB master bus architecture with independent FIFO to optimize the bandwidth of the system, based on a complex bus matrix architecture.

The two DMA controllers have 16 streams in total (8 for each controller), each dedicated to managing memory access requests from one or more peripherals. Each stream can have up to 8 channels (requests) in total. And each has an arbiter for handling the priority between DMA requests.

### 9.2 DMA main features

The main DMA features are:

- Dual AHB master bus architecture, one dedicated to memory accesses and one dedicated to peripheral accesses
- AHB slave programming interface supporting only 32-bit accesses
- 8 streams for each DMA controller, up to 8 channels (requests) per stream
- Four-word depth 32 first-in, first-out memory buffers (FIFOs) per stream, that can be used in FIFO mode or direct mode:
  - FIFO mode: with threshold level software selectable between 1/4, 1/2 or 3/4 of the FIFO size
  - Direct modeEach DMA request immediately initiates a transfer from/to the memory. When it is configured in direct mode (FIFO disabled), to transfer data in memory-to-peripheral mode, the DMA preloads only one data from the memory to the internal

FIFO to ensure an immediate data transfer as soon as a DMA request is triggered by a peripheral.

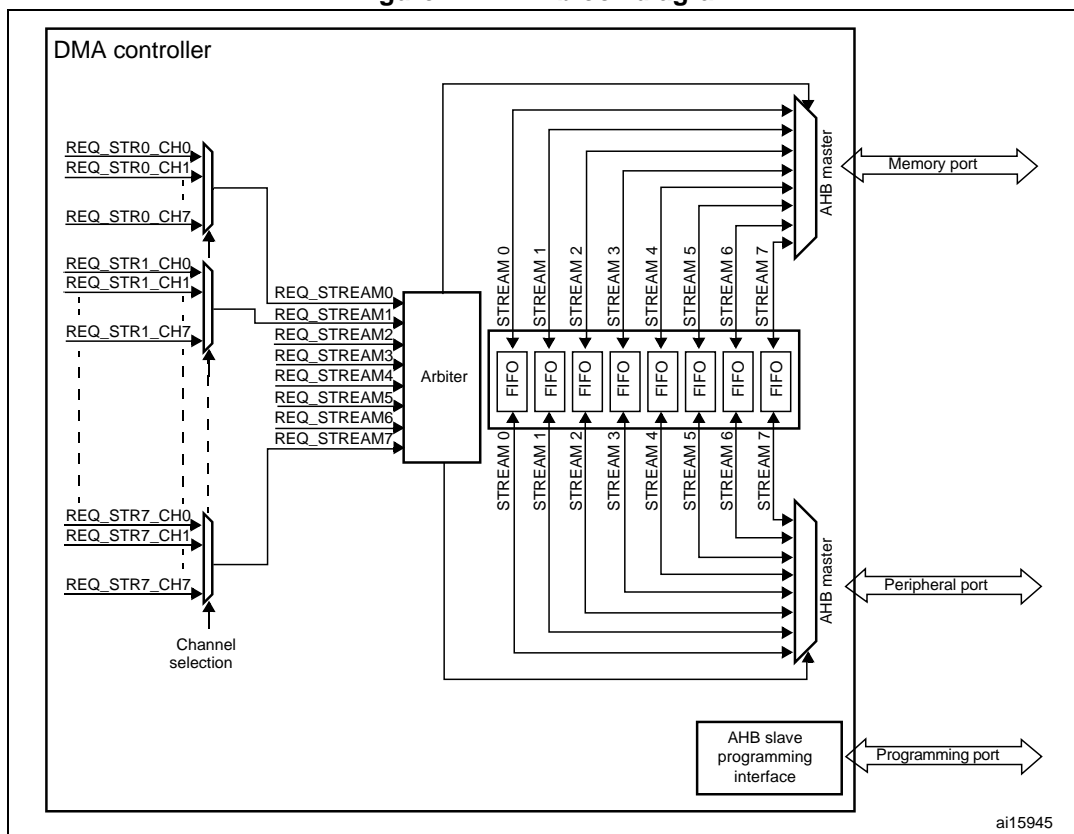
- Each stream can be configured by hardware to be:
  - a regular channel that supports peripheral-to-memory, memory-to-peripheral and memory-to-memory transfers
  - a double buffer channel that also supports double buffering on the memory side
- Each of the 8 streams are connected to dedicated hardware DMA channels (requests)
- Priorities between DMA stream requests are software-programmable (4 levels consisting of very high, high, medium, low) or hardware in case of equality (request 0 has priority over request 1, etc.)
- Each stream also supports software trigger for memory-to-memory transfers (only available for the DMA2 controller)
- Each stream request can be selected among up to 8 possible channel requests. This selection is software-configurable and allows several peripherals to initiate DMA requests
- The number of data items to be transferred can be managed either by the DMA controller or by the peripheral:
  - DMA flow controller: the number of data items to be transferred is software-programmable from 1 to 65535
  - Peripheral flow controller: the number of data items to be transferred is unknown and controlled by the source or the destination peripheral that signals the end of the transfer by hardware
- Independent source and destination transfer width (byte, half-word, word): when the data widths of the source and destination are not equal, the DMA automatically packs/unpacks the necessary transfers to optimize the bandwidth. This feature is only available in FIFO mode
- Incrementing or nonincrementing addressing for source and destination
- Supports incremental burst transfers of 4, 8 or 16 beats. The size of the burst is software-configurable, usually equal to half the FIFO size of the peripheral
- Each stream supports circular buffer management
- 5 event flags (DMA Half Transfer, DMA Transfer complete, DMA Transfer Error, DMA FIFO Error, Direct Mode Error) logically ORed together in a single interrupt request for each stream

### 9.3 DMA functional description

#### 9.3.1 General description

Figure 22 shows the block diagram of a DMA.

Figure 22. DMA block diagram



The DMA controller performs direct memory transfer: as an AHB master, it can take the control of the AHB bus matrix to initiate AHB transactions.

It can carry out the following transactions:

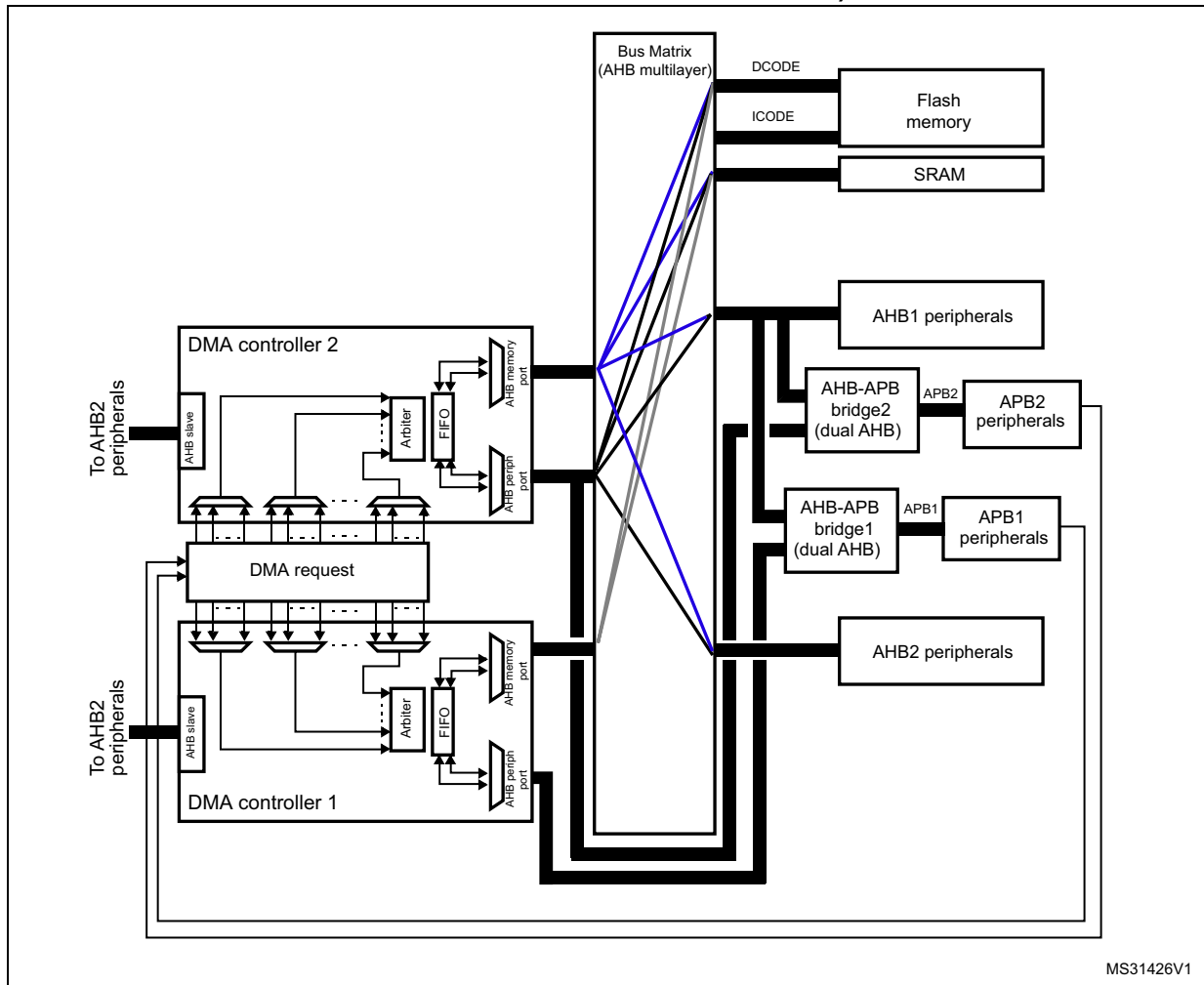
- peripheral-to-memory
- memory-to-peripheral
- memory-to-memory

The DMA controller provides two AHB master ports: the *AHB memory port*, intended to be connected to memories and the *AHB peripheral port*, intended to be connected to peripherals. However, to allow memory-to-memory transfers, the *AHB peripheral port* must also have access to the memories.

The AHB slave port is used to program the DMA controller (it supports only 32-bit accesses).

See Figure 23 for the implementation of the system of two DMA controllers.

Figure 23. System implementation of the two DMA controllers (STM32F401xB/C and STM32F401xD/E)



1. The DMA1 controller AHB peripheral port is not connected to the bus matrix like DMA2 controller. As a result, only DMA2 streams are able to perform memory-to-memory transfers.

### 9.3.2 DMA transactions

A DMA transaction consists of a sequence of a given number of data transfers. The number of data items to be transferred and their width (8-bit, 16-bit or 32-bit) are software-programmable.

Each DMA transfer consists of three operations:

- A loading from the peripheral data register or a location in memory, addressed through the DMA\_SxPAR or DMA\_SxM0AR register
- A storage of the data loaded to the peripheral data register or a location in memory addressed through the DMA\_SxPAR or DMA\_SxM0AR register
- A post-decrement of the DMA\_SxNDTR register, which contains the number of transactions that still have to be performed

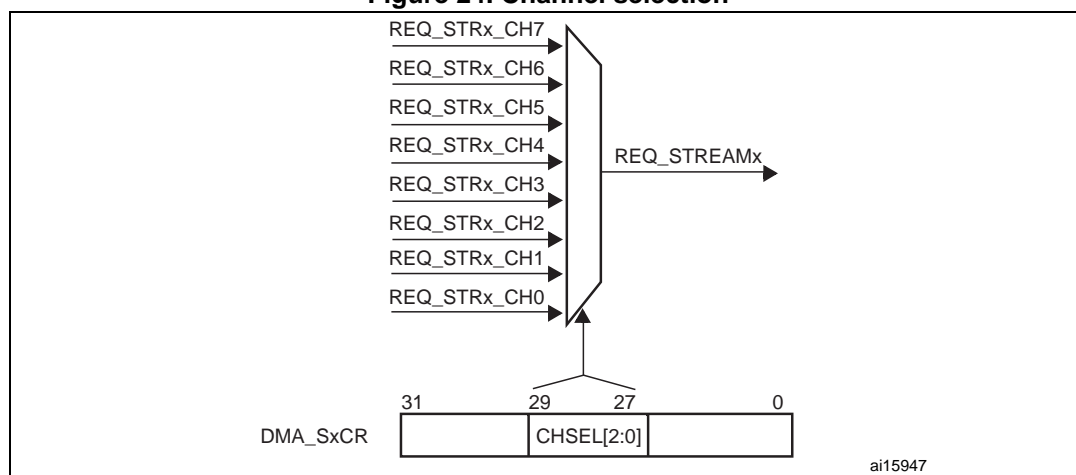
After an event, the peripheral sends a request signal to the DMA controller. The DMA controller serves the request depending on the channel priorities. As soon as the DMA

controller accesses the peripheral, an Acknowledge signal is sent to the peripheral by the DMA controller. The peripheral releases its request as soon as it gets the Acknowledge signal from the DMA controller. Once the request has been deasserted by the peripheral, the DMA controller releases the Acknowledge signal. If there are more requests, the peripheral can initiate the next transaction.

### 9.3.3 Channel selection

Each stream is associated with a DMA request that can be selected out of 8 possible channel requests. The selection is controlled by the CHSEL[2:0] bits in the DMA\_SxCR register.

Figure 24. Channel selection



The 8 requests from the peripherals (TIM, ADC, SPI, I2C, etc.) are independently connected to each channel and their connection depends on the product implementation.

Table 81 and Table 83 give examples of DMA request mappings.

Table 28. DMA1 request mapping (STM32F401xB/C and STM32F401xD/E)

Peripheral requests	Stream 0	Stream 1	Stream 2	Stream 3	Stream 4	Stream 5	Stream 6	Stream 7
Channel 0	SPI3_RX		SPI3_RX	SPI2_RX	SPI2_TX	SPI3_TX		SPI3_TX
Channel 1	I2C1_RX	I2C3_RX				I2C1_RX	I2C1_TX	I2C1_TX
Channel 2	TIM4_CH1		I2S3_EXT_RX	TIM4_CH2	I2S2_EXT_TX	I2S3_EXT_TX	TIM4_UP	TIM4_CH3
Channel 3	I2S3_EXT_RX	TIM2_UP TIM2_CH3	I2C3_RX	I2S2_EXT_RX	I2C3_TX	TIM2_CH1	TIM2_CH2 TIM2_CH4	TIM2_UP TIM2_CH4
Channel 4						USART2_RX	USART2_TX	
Channel 5			TIM3_CH4 TIM3_UP		TIM3_CH1 TIM3_TRIG	TIM3_CH2		TIM3_CH3
Channel 6	TIM5_CH3 TIM5_UP	TIM5_CH4 TIM5_TRIG	TIM5_CH1	TIM5_CH4 TIM5_TRIG	TIM5_CH2	I2C3_TX	TIM5_UP	
Channel 7			I2C2_RX	I2C2_RX				I2C2_TX

**Table 29. DMA2 request mapping (STM32F401xB/C and STM32F401xD/E)**

Peripheral requests	Stream 0	Stream 1	Stream 2	Stream 3	Stream 4	Stream 5	Stream 6	Stream 7
Channel 0	ADC1				ADC1		TIM1_CH1 TIM1_CH2 TIM1_CH3	
Channel 1								
Channel 2								
Channel 3	SPI1_RX		SPI1_RX	SPI1_TX		SPI1_TX		
Channel 4	SPI4_RX	SPI4_TX	USART1_RX	SDIO		USART1_RX	SDIO	USART1_TX
Channel 5		USART6_RX	USART6_RX	SPI4_RX	SPI4_TX		USART6_TX	USART6_TX
Channel 6	TIM1_TRIG	TIM1_CH1	TIM1_CH2	TIM1_CH1	TIM1_CH4 TIM1_TRIG TIM1_COM	TIM1_UP	TIM1_CH3	
Channel 7								

### 9.3.4 Arbiter

An arbiter manages the 8 DMA stream requests based on their priority for each of the two AHB master ports (memory and peripheral ports) and launches the peripheral/memory access sequences.

Priorities are managed in two stages:

- Software: each stream priority can be configured in the DMA\_SxCR register. There are four levels:
  - Very high priority
  - High priority
  - Medium priority
  - Low priority
- Hardware: If two requests have the same software priority level, the stream with the lower number takes priority over the stream with the higher number. For example, Stream 2 takes priority over Stream 4.

### 9.3.5 DMA streams

Each of the 8 DMA controller streams provides a unidirectional transfer link between a source and a destination.

Each stream can be configured to perform:

- Regular type transactions: memory-to-peripherals, peripherals-to-memory or memory-to-memory transfers
- Double-buffer type transactions: double buffer transfers using two memory pointers for the memory (while the DMA is reading/writing from/to a buffer, the application can write/read to/from the other buffer).

The amount of data to be transferred (up to 65535) is programmable and related to the source width of the peripheral that requests the DMA transfer connected to the peripheral AHB port. The register that contains the amount of data items to be transferred is decremented after each transaction.

### 9.3.6 Source, destination and transfer modes

Both source and destination transfers can address peripherals and memories in the entire 4 GB area, at addresses comprised between 0x0000 0000 and 0xFFFF FFFF.

The direction is configured using the DIR[1:0] bits in the DMA\_SxCR register and offers three possibilities: memory-to-peripheral, peripheral-to-memory or memory-to-memory transfers. [Table 30](#) describes the corresponding source and destination addresses.

**Table 30. Source and destination address**

Bits DIR[1:0] of the DMA_SxCR register	Direction	Source address	Destination address
00	Peripheral-to-memory	DMA_SxPAR	DMA_SxM0AR
01	Memory-to-peripheral	DMA_SxM0AR	DMA_SxPAR
10	Memory-to-memory	DMA_SxPAR	DMA_SxM0AR
11	reserved	-	-

When the data width (programmed in the PSIZE or MSIZE bits in the DMA\_SxCR register) is a half-word or a word, respectively, the peripheral or memory address written into the DMA\_SxPAR or DMA\_SxM0AR/M1AR registers has to be aligned on a word or half-word address boundary, respectively.

#### Peripheral-to-memory mode

[Figure 25](#) describes this mode.

When this mode is enabled (by setting the bit EN in the DMA\_SxCR register), each time a peripheral request occurs, the stream initiates a transfer from the source to fill the FIFO.

When the threshold level of the FIFO is reached, the contents of the FIFO are drained and stored into the destination.

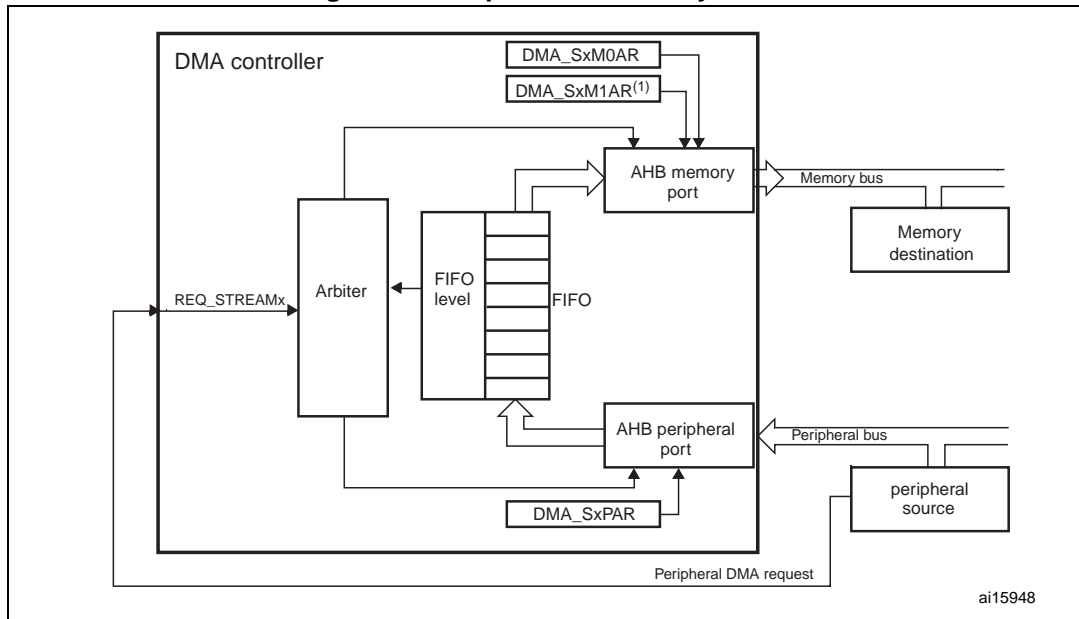
The transfer stops once the DMA\_SxNDTR register reaches zero, when the peripheral requests the end of transfers (in case of a peripheral flow controller) or when the EN bit in the DMA\_SxCR register is cleared by software.

In direct mode (when the DMDIS value in the DMA\_SxFCR register is '0'), the threshold level of the FIFO is not used: after each single data transfer from the peripheral to the FIFO, the corresponding data are immediately drained and stored into the destination.

The stream has access to the AHB source or destination port only if the arbitration of the corresponding stream is won. This arbitration is performed using the priority defined for each stream using the PL[1:0] bits in the DMA\_SxCR register.



Figure 25. Peripheral-to-memory mode



1. For double-buffer mode.

### Memory-to-peripheral mode

Figure 26 describes this mode.

When this mode is enabled (by setting the EN bit in the DMA\_SxCR register), the stream immediately initiates transfers from the source to entirely fill the FIFO.

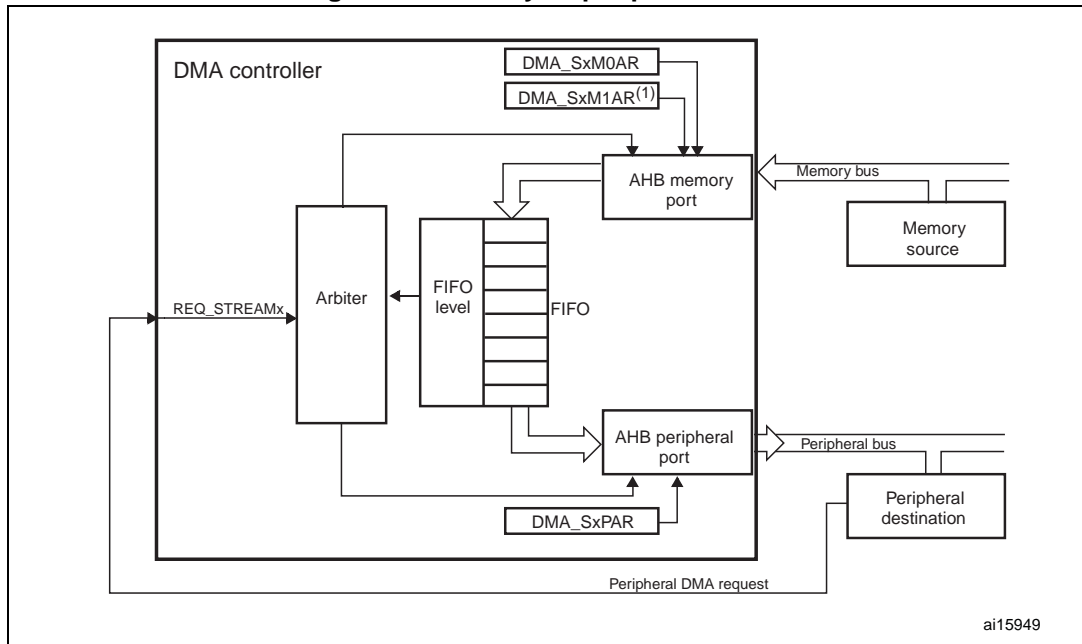
Each time a peripheral request occurs, the contents of the FIFO are drained and stored into the destination. When the level of the FIFO is lower than or equal to the predefined threshold level, the FIFO is fully reloaded with data from the memory.

The transfer stops once the DMA\_SxNDTR register reaches zero, when the peripheral requests the end of transfers (in case of a peripheral flow controller) or when the EN bit in the DMA\_SxCR register is cleared by software.

In direct mode (when the DMDIS value in the DMA\_SxFCR register is '0'), the threshold level of the FIFO is not used. Once the stream is enabled, the DMA preloads the first data to transfer into an internal FIFO. As soon as the peripheral requests a data transfer, the DMA transfers the preloaded value into the configured destination. It then reloads again the empty internal FIFO with the next data to be transfer. The preloaded data size corresponds to the value of the PSIZE bitfield in the DMA\_SxCR register.

The stream has access to the AHB source or destination port only if the arbitration of the corresponding stream is won. This arbitration is performed using the priority defined for each stream using the PL[1:0] bits in the DMA\_SxCR register.

Figure 26. Memory-to-peripheral mode



1. For double-buffer mode.

**Memory-to-memory mode**

The DMA channels can also work without being triggered by a request from a peripheral. This is the memory-to-memory mode, described in [Figure 27](#).

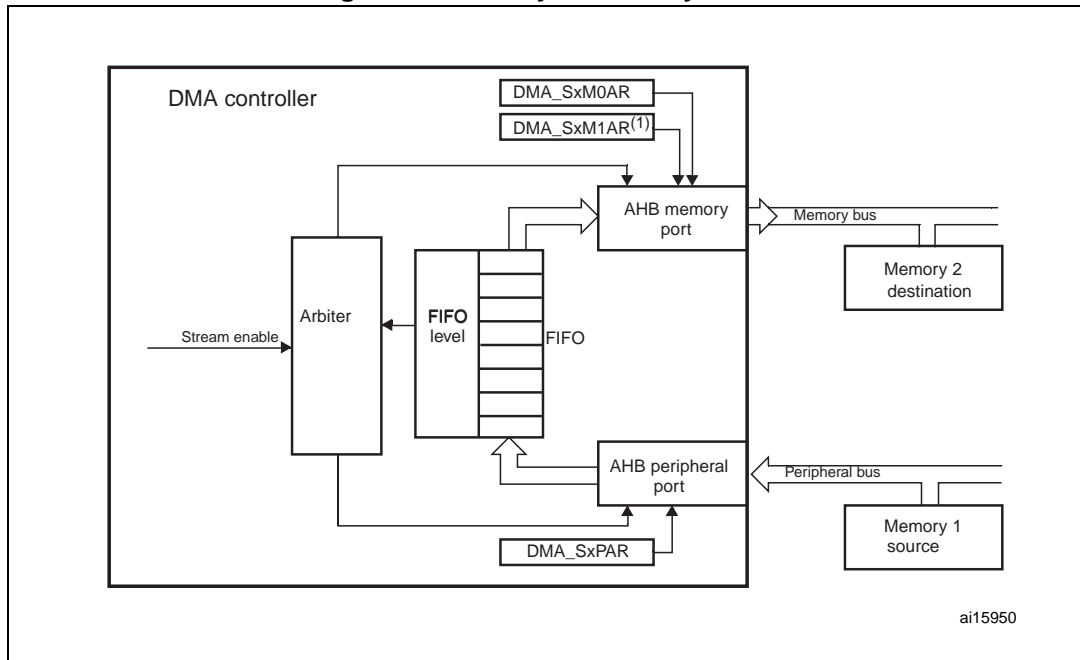
When the stream is enabled by setting the Enable bit (EN) in the DMA\_SxCR register, the stream immediately starts to fill the FIFO up to the threshold level. When the threshold level is reached, the FIFO contents are drained and stored into the destination.

The transfer stops once the DMA\_SxNDTR register reaches zero or when the EN bit in the DMA\_SxCR register is cleared by software.

The stream has access to the AHB source or destination port only if the arbitration of the corresponding stream is won. This arbitration is performed using the priority defined for each stream using the PL[1:0] bits in the DMA\_SxCR register.

*Note: When memory-to-memory mode is used, the Circular and direct modes are not allowed. Only the DMA2 controller is able to perform memory-to-memory transfers.*

Figure 27. Memory-to-memory mode



1. For double-buffer mode.

### 9.3.7 Pointer incrementation

Peripheral and memory pointers can optionally be automatically post-incremented or kept constant after each transfer depending on the PINC and MINC bits in the DMA\_SxCR register.

Disabling the Increment mode is useful when the peripheral source or destination data are accessed through a single register.

If the Increment mode is enabled, the address of the next transfer will be the address of the previous one incremented by 1 (for bytes), 2 (for half-words) or 4 (for words) depending on the data width programmed in the PSIZE or MSIZE bits in the DMA\_SxCR register.

In order to optimize the packing operation, it is possible to fix the increment offset size for the peripheral address whatever the size of the data transferred on the AHB peripheral port. The PINCOS bit in the DMA\_SxCR register is used to align the increment offset size with the data size on the peripheral AHB port, or on a 32-bit address (the address is then incremented by 4). The PINCOS bit has an impact on the AHB peripheral port only.

If PINCOS bit is set, the address of the next transfer is the address of the previous one incremented by 4 (automatically aligned on a 32-bit address) whatever the PSIZE value. The AHB memory port, however, is not impacted by this operation.

### 9.3.8 Circular mode

The Circular mode is available to handle circular buffers and continuous data flows (e.g. ADC scan mode). This feature can be enabled using the CIRC bit in the DMA\_SxCR register.

When the circular mode is activated, the number of data items to be transferred is automatically reloaded with the initial value programmed during the stream configuration phase, and the DMA requests continue to be served.

*Note:* In the circular mode, it is mandatory to respect the following rule in case of a burst mode configured for memory:

$DMA\_SxNDTR = \text{Multiple of } ((Mburst\ beat) \times (Msize)/(Psize)), \text{ where:}$

- $(Mburst\ beat) = 4, 8 \text{ or } 16$  (depending on the MBURST bits in the DMA\_SxCR register)
- $((Msize)/(Psize)) = 1, 2, 4, 1/2 \text{ or } 1/4$  (Msize and Psize represent the MSIZE and PSIZE bits in the DMA\_SxCR register. They are byte dependent)
- $DMA\_SxNDTR = \text{Number of data items to transfer on the AHB peripheral port}$

For example: Mburst beat = 8 (INCR8), MSIZE = '00' (byte) and PSIZE = '01' (half-word), in this case: DMA\_SxNDTR must be a multiple of  $(8 \times 1/2 = 4)$ .

If this formula is not respected, the DMA behavior and data integrity are not guaranteed.

NDTR must also be a multiple of the Peripheral burst size multiplied by the peripheral data size, otherwise this could result in a bad DMA behavior.

### 9.3.9 Double buffer mode

This mode is available for all the DMA1 and DMA2 streams.

The Double buffer mode is enabled by setting the DBM bit in the DMA\_SxCR register.

A double-buffer stream works as a regular (single buffer) stream with the difference that it has two memory pointers. When the Double buffer mode is enabled, the Circular mode is automatically enabled (CIRC bit in DMA\_SxCR is don't care) and at each end of transaction, the memory pointers are swapped.

In this mode, the DMA controller swaps from one memory target to another at each end of transaction. This allows the software to process one memory area while the second memory area is being filled/used by the DMA transfer. The double-buffer stream can work in both directions (the memory can be either the source or the destination) as described in [Table 31: Source and destination address registers in Double buffer mode \(DBM=1\)](#).

*Note:* In Double buffer mode, it is possible to update the base address for the AHB memory port on-the-fly (DMA\_SxM0AR or DMA\_SxM1AR) when the stream is enabled, by respecting the following conditions:

- When the CT bit is '0' in the DMA\_SxCR register, the DMA\_SxM1AR register can be written. Attempting to write to this register while CT = '1' sets an error flag (TEIF) and the stream is automatically disabled.
- When the CT bit is '1' in the DMA\_SxCR register, the DMA\_SxM0AR register can be written. Attempting to write to this register while CT = '0', sets an error flag (TEIF) and the stream is automatically disabled.

To avoid any error condition, it is advised to change the base address as soon as the TCIF flag is asserted because, at this point, the targeted memory must have changed from

memory 0 to 1 (or from 1 to 0) depending on the value of CT in the DMA\_SxCR register in accordance with one of the two above conditions.

For all the other modes (except the Double buffer mode), the memory address registers are write-protected as soon as the stream is enabled.

**Table 31. Source and destination address registers in Double buffer mode (DBM=1)**

Bits DIR[1:0] of the DMA_SxCR register	Direction	Source address	Destination address
00	Peripheral-to-memory	DMA_SxPAR	DMA_SxM0AR / DMA_SxM1AR
01	Memory-to-peripheral	DMA_SxM0AR / DMA_SxM1AR	DMA_SxPAR
10	Not allowed <sup>(1)</sup>		
11	Reserved	-	-

1. When the Double buffer mode is enabled, the Circular mode is automatically enabled. Since the memory-to-memory mode is not compatible with the Circular mode, when the Double buffer mode is enabled, it is not allowed to configure the memory-to-memory mode.

### 9.3.10 Programmable data width, packing/unpacking, endianness

The number of data items to be transferred has to be programmed into DMA\_SxNDTR (number of data items to transfer bit, NDT) before enabling the stream (except when the flow controller is the peripheral, PFCTRL bit in DMA\_SxCR is set).

When using the internal FIFO, the data widths of the source and destination data are programmable through the PSIZE and MSIZE bits in the DMA\_SxCR register (can be 8-, 16- or 32-bit).

When PSIZE and MSIZE are not equal:

- The data width of the number of data items to transfer, configured in the DMA\_SxNDTR register is equal to the width of the peripheral bus (configured by the PSIZE bits in the DMA\_SxCR register). For instance, in case of peripheral-to-memory, memory-to-peripheral or memory-to-memory transfers and if the PSIZE[1:0] bits are configured for half-word, the number of bytes to be transferred is equal to  $2 \times \text{NDT}$ .
- The DMA controller only copes with little-endian addressing for both source and destination. This is described in [Table 32: Packing/unpacking & endian behavior \(bit PINC = MINC = 1\)](#).

This packing/unpacking procedure may present a risk of data corruption when the operation is interrupted before the data are completely packed/unpacked. So, to ensure data coherence, the stream may be configured to generate burst transfers: in this case, each group of transfers belonging to a burst are indivisible (refer to [Section 9.3.11: Single and burst transfers](#)).

In direct mode (DMDIS = 0 in the DMA\_SxFCR register), the packing/unpacking of data is not possible. In this case, it is not allowed to have different source and destination transfer data widths: both are equal and defined by the PSIZE bits in the DMA\_SxCR MSIZE bits are don't care).

Table 32. Packing/unpacking & endian behavior (bit PINC = MINC = 1)

AHB memory port width	AHB peripheral port width	Number of data items to transfer (NDT)	Memory transfer number	Memory port address / byte lane	Peripheral transfer number	Peripheral port address / byte lane	
						PINCOS = 1	PINCOS = 0
8	8	4	1	0x0 / B0[7:0]	1	0x0 / B0[7:0]	0x0 / B0[7:0]
			2	0x1 / B1[7:0]	2	0x4 / B1[7:0]	0x1 / B1[7:0]
			3	0x2 / B2[7:0]	3	0x8 / B2[7:0]	0x2 / B2[7:0]
			4	0x3 / B3[7:0]	4	0xC / B3[7:0]	0x3 / B3[7:0]
8	16	2	1	0x0 / B0[7:0]	1	0x0 / B1 B0[15:0]	0x0 / B1 B0[15:0]
			2	0x1 / B1[7:0]	2	0x4 / B3 B2[15:0]	0x2 / B3 B2[15:0]
			3	0x2 / B2[7:0]			
			4	0x3 / B3[7:0]			
8	32	1	1	0x0 / B0[7:0]	1	0x0 / B3 B2 B1 B0[31:0]	0x0 / B3 B2 B1 B0[31:0]
			2	0x1 / B1[7:0]			
			3	0x2 / B2[7:0]			
			4	0x3 / B3[7:0]			
16	8	4	1	0x0 / B1 B0[15:0]	1	0x0 / B0[7:0]	0x0 / B0[7:0]
			2	0x2 / B3 B2[15:0]	2	0x4 / B1[7:0]	0x1 / B1[7:0]
			3		3	0x8 / B2[7:0]	0x2 / B2[7:0]
			4		4	0xC / B3[7:0]	0x3 / B3[7:0]
16	16	2	1	0x0 / B1 B0[15:0]	1	0x0 / B1 B0[15:0]	0x0 / B1 B0[15:0]
			2	0x2 / B1 B0[15:0]	2	0x4 / B3 B2[15:0]	0x2 / B3 B2[15:0]
16	32	1	1	0x0 / B1 B0[15:0]	1	0x0 / B3 B2 B1 B0[31:0]	0x0 / B3 B2 B1 B0[31:0]
			2	0x2 / B3 B2[15:0]			
32	8	4	1	0x0 / B3 B2 B1 B0[31:0]	1	0x0 / B0[7:0]	0x0 / B0[7:0]
			2		2	0x4 / B1[7:0]	0x1 / B1[7:0]
			3		3	0x8 / B2[7:0]	0x2 / B2[7:0]
			4		4	0xC / B3[7:0]	0x3 / B3[7:0]
32	16	2	1	0x0 / B3 B2 B1 B0 [31:0]	1	0x0 / B1 B0[15:0]	0x0 / B1 B0[15:0]
			2		2	0x4 / B3 B2[15:0]	0x2 / B3 B2[15:0]
32	32	1	1	0x0 / B3 B2 B1 B0 [31:0]	1	0x0 / B3 B2 B1 B0 [31:0]	0x0 / B3 B2 B1 B0 [31:0]

Note: Peripheral port may be the source or the destination (it could also be the memory source in the case of memory-to-memory transfer).

PSIZE, MSIZE and NDT[15:0] have to be configured so as to ensure that the last transfer will not be incomplete. This can occur when the data width of the peripheral port (PSIZE bits) is lower than the data width of the memory port (MSIZE bits). This constraint is summarized in [Table 33](#).

Table 33. Restriction on NDT versus PSIZE and MSIZE

PSIZE[1:0] of DMA_SxCR	MSIZE[1:0] of DMA_SxCR	NDT[15:0] of DMA_SxNDTR
00 (8-bit)	01 (16-bit)	must be a multiple of 2
00 (8-bit)	10 (32-bit)	must be a multiple of 4
01 (16-bit)	10 (32-bit)	must be a multiple of 2

### 9.3.11 Single and burst transfers

The DMA controller can generate single transfers or incremental burst transfers of 4, 8 or 16 beats.

The size of the burst is configured by software independently for the two AHB ports by using the MBURST[1:0] and PBURST[1:0] bits in the DMA\_SxCR register.

The burst size indicates the number of beats in the burst, not the number of bytes transferred.

To ensure data coherence, each group of transfers that form a burst are indivisible: AHB transfers are locked and the arbiter of the AHB bus matrix does not degrant the DMA master during the sequence of the burst transfer.

Depending on the single or burst configuration, each DMA request initiates a different number of transfers on the AHB peripheral port:

- When the AHB peripheral port is configured for single transfers, each DMA request generates a data transfer of a byte, half-word or word depending on the PSIZE[1:0] bits in the DMA\_SxCR register
- When the AHB peripheral port is configured for burst transfers, each DMA request generates 4,8 or 16 beats of byte, half word or word transfers depending on the PBURST[1:0] and PSIZE[1:0] bits in the DMA\_SxCR register.

The same as above has to be considered for the AHB memory port considering the MBURST and MSIZE bits.

In direct mode, the stream can only generate single transfers and the MBURST[1:0] and PBURST[1:0] bits are forced by hardware.

The address pointers (DMA\_SxPAR or DMA\_SxM0AR registers) must be chosen so as to ensure that all transfers within a burst block are aligned on the address boundary equal to the size of the transfer.

The burst configuration has to be selected in order to respect the AHB protocol, where bursts must *not* cross the 1 KB address boundary because the minimum address space that can be allocated to a single slave is 1 KB. This means that the 1 KB address boundary should not be crossed by a burst block transfer, otherwise an AHB error would be generated, that is not reported by the DMA registers.

### 9.3.12 FIFO

#### FIFO structure

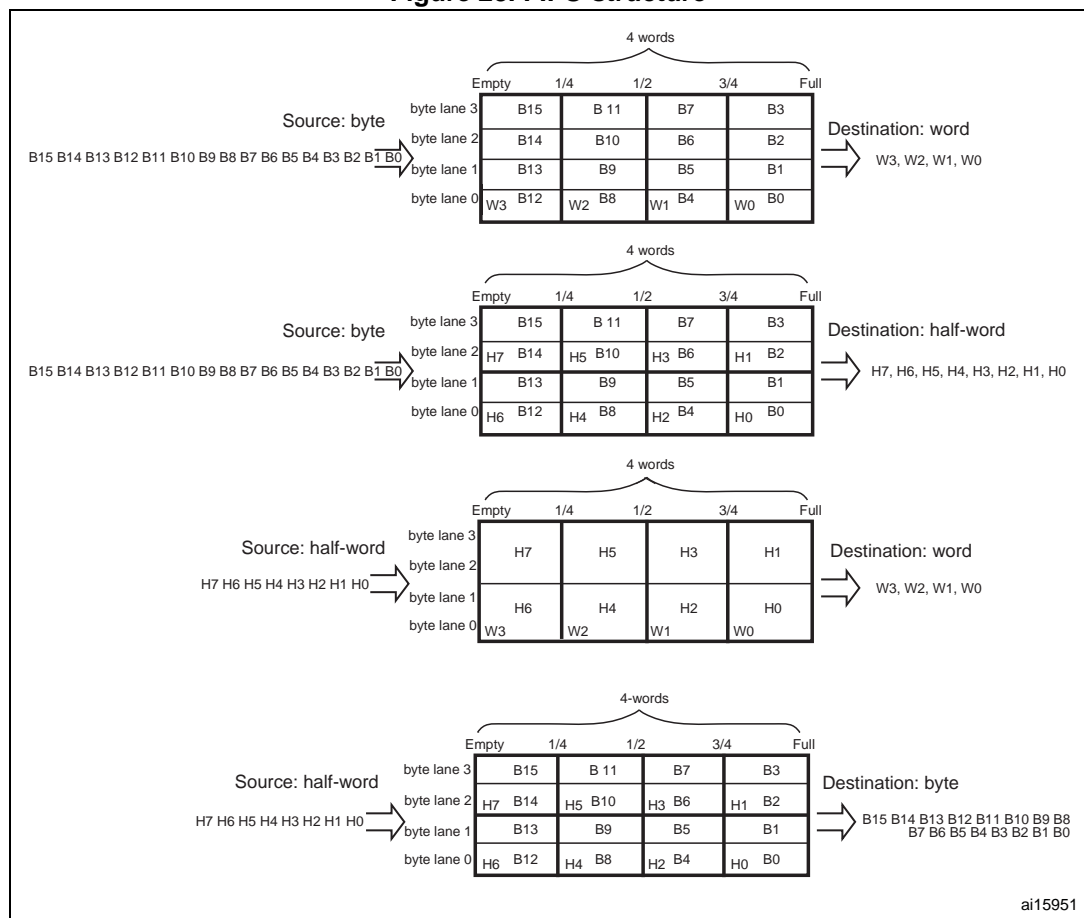
The FIFO is used to temporarily store data coming from the source before transmitting them to the destination.

Each stream has an independent 4-word FIFO and the threshold level is software-configurable between 1/4, 1/2, 3/4 or full.

To enable the use of the FIFO threshold level, the direct mode must be disabled by setting the DMDIS bit in the DMA\_SxFCR register.

The structure of the FIFO differs depending on the source and destination data widths, and is described in [Figure 28: FIFO structure](#).

Figure 28. FIFO structure



#### FIFO threshold and burst configuration

Caution is required when choosing the FIFO threshold (bits FTH[1:0] of the DMA\_SxFCR register) and the size of the memory burst (MBURST[1:0] of the DMA\_SxCR register): The content pointed by the FIFO threshold must exactly match to an integer number of memory burst transfers. If this is not in the case, a FIFO error (flag FEIFx of the DMA\_HISR or DMA\_LISR register) will be generated when the stream is enabled, then the stream will be automatically disabled. The allowed and forbidden configurations are described in the



Table 34: FIFO threshold configurations.

Table 34. FIFO threshold configurations

MSIZE	FIFO level	MBURST = INCR4	MBURST = INCR8	MBURST = INCR16
Byte	1/4	1 burst of 4 beats	forbidden	forbidden
	1/2	2 bursts of 4 beats	1 burst of 8 beats	
	3/4	3 bursts of 4 beats	forbidden	
	Full	4 bursts of 4 beats	2 bursts of 8 beats	1 burst of 16 beats
Half-word	1/4	forbidden	forbidden	forbidden
	1/2	1 burst of 4 beats		
	3/4	forbidden		
	Full	2 bursts of 4 beats	1 burst of 8 beats	
Word	1/4	forbidden	forbidden	forbidden
	1/2			
	3/4			
	Full	1 burst of 4 beats		

In all cases, the burst size multiplied by the data size must not exceed the FIFO size (data size can be: 1 (byte), 2 (half-word) or 4 (word)).

Incomplete Burst transfer at the end of a DMA transfer may happen if one of the following conditions occurs:

- For the AHB peripheral port configuration: the total number of data items (set in the DMA\_SxNDTR register) is not a multiple of the burst size multiplied by the data size
- For the AHB memory port configuration: the number of remaining data items in the FIFO to be transferred to the memory is not a multiple of the burst size multiplied by the data size

In such cases, the remaining data to be transferred will be managed in single mode by the DMA, even if a burst transaction was requested during the DMA stream configuration.

*Note: When burst transfers are requested on the peripheral AHB port and the FIFO is used (DMDIS = 1 in the DMA\_SxCR register), it is mandatory to respect the following rule to avoid permanent underrun or overrun conditions, depending on the DMA stream direction:*

*If (PBURST × PSIZE) = FIFO\_SIZE (4 words), FIFO\_Threshold = 3/4 is forbidden with PSIZE = 1, 2 or 4 and PBURST = 4, 8 or 16.*

*This rule ensures that enough FIFO space at a time will be free to serve the request from the peripheral.*

### FIFO flush

The FIFO can be flushed when the stream is disabled by resetting the EN bit in the DMA\_SxCR register and when the stream is configured to manage peripheral-to-memory or memory-to-memory transfers: If some data are still present in the FIFO when the stream is disabled, the DMA controller continues transferring the remaining data to the destination (even though stream is effectively disabled). When this flush is completed, the transfer complete status bit (TCIFx) in the DMA\_LISR or DMA\_HISR register is set.

The remaining data counter DMA\_SxNDTR keeps the value in this case to indicate how many data items are currently available in the destination memory.

Note that during the FIFO flush operation, if the number of remaining data items in the FIFO to be transferred to memory (in bytes) is less than the memory data width (for example 2 bytes in FIFO while MSIZE is configured to word), data will be sent with the data width set in the MSIZE bit in the DMA\_SxCR register. This means that memory will be written with an undesired value. The software may read the DMA\_SxNDTR register to determine the memory area that contains the good data (start address and last address).

If the number of remaining data items in the FIFO is lower than a burst size (if the MBURST bits in DMA\_SxCR register are set to configure the stream to manage burst on the AHB memory port), single transactions will be generated to complete the FIFO flush.

### Direct mode

By default, the FIFO operates in direct mode (DMDIS bit in the DMA\_SxFCR is reset) and the FIFO threshold level is not used. This mode is useful when the system requires an immediate and single transfer to or from the memory after each DMA request.

When the DMA is configured in direct mode (FIFO disabled), to transfer data in memory-to-peripheral mode, the DMA preloads one data from the memory to the internal FIFO to ensure an immediate data transfer as soon as a DMA request is triggered by a peripheral.

To avoid saturating the FIFO, it is recommended to configure the corresponding stream with a high priority.

This mode is restricted to transfers where:

- The source and destination transfer widths are equal and both defined by the PSIZE[1:0] bits in DMA\_SxCR (MSIZE[1:0] bits are don't care)
- Burst transfers are not possible (PBURST[1:0] and MBURST[1:0] bits in DMA\_SxCR are don't care)

Direct mode must not be used when implementing memory-to-memory transfers.

### 9.3.13 DMA transfer completion

Different events can generate an end of transfer by setting the TCIFx bit in the DMA\_LISR or DMA\_HISR status register:

- In DMA flow controller mode:
  - The DMA\_SxNDTR counter has reached zero in the memory-to-peripheral mode
  - The stream is disabled before the end of transfer (by clearing the EN bit in the DMA\_SxCR register) and (when transfers are peripheral-to-memory or memory-

to-memory) all the remaining data have been flushed from the FIFO into the memory

- In Peripheral flow controller mode:
  - The last external burst or single request has been generated from the peripheral and (when the DMA is operating in peripheral-to-memory mode) the remaining data have been transferred from the FIFO into the memory
  - The stream is disabled by software, and (when the DMA is operating in peripheral-to-memory mode) the remaining data have been transferred from the FIFO into the memory

*Note:* The transfer completion is dependent on the remaining data in FIFO to be transferred into memory only in the case of peripheral-to-memory mode. This condition is not applicable in memory-to-peripheral mode.

If the stream is configured in noncircular mode, after the end of the transfer (that is when the number of data to be transferred reaches zero), the DMA is stopped (EN bit in DMA\_SxCR register is cleared by Hardware) and no DMA request is served unless the software reprograms the stream and re-enables it (by setting the EN bit in the DMA\_SxCR register).

### 9.3.14 DMA transfer suspension

At any time, a DMA transfer can be suspended to be restarted later on or to be definitively disabled before the end of the DMA transfer.

There are two cases:

- The stream disables the transfer with no later-on restart from the point where it was stopped. There is no particular action to do, except to clear the EN bit in the DMA\_SxCR register to disable the stream. The stream may take time to be disabled (ongoing transfer is completed first). The transfer complete interrupt flag (TCIF in the DMA\_LISR or DMA\_HISR register) is set in order to indicate the end of transfer. The value of the EN bit in DMA\_SxCR is now '0' to confirm the stream interruption. The DMA\_SxNDTR register contains the number of remaining data items at the moment when the stream was stopped so that the software can determine how many data items have been transferred before the stream was interrupted.
- The stream suspends the transfer before the number of remaining data items to be transferred in the DMA\_SxNDTR register reaches 0. The aim is to restart the transfer later by re-enabling the stream. In order to restart from the point where the transfer was stopped, the software has to read the DMA\_SxNDTR register after disabling the stream by writing the EN bit in DMA\_SxCR register (and then checking that it is at '0') to know the number of data items already collected. Then:
  - The peripheral and/or memory addresses have to be updated in order to adjust the address pointers
  - The SxNDTR register has to be updated with the remaining number of data items to be transferred (the value read when the stream was disabled)
  - The stream may then be re-enabled to restart the transfer from the point it was stopped

*Note:* Note that a Transfer complete interrupt flag (TCIF in DMA\_LISR or DMA\_HISR) is set to indicate the end of transfer due to the stream interruption.

### 9.3.15 Flow controller

The entity that controls the number of data to be transferred is known as the flow controller. This flow controller is configured independently for each stream using the PFCTRL bit in the DMA\_SxCR register.

The flow controller can be:

- The DMA controller: in this case, the number of data items to be transferred is programmed by software into the DMA\_SxNDTR register before the DMA stream is enabled.
- The peripheral source or destination: this is the case when the number of data items to be transferred is unknown. The peripheral indicates by hardware to the DMA controller when the last data are being transferred. This feature is only supported for peripherals which are able to signal the end of the transfer, that is:
  - SDIO

When the peripheral flow controller is used for a given stream, the value written into the DMA\_SxNDTR has no effect on the DMA transfer. Actually, whatever the value written, it will be forced by hardware to 0xFFFF as soon as the stream is enabled, to respect the following schemes:

- Anticipated stream interruption: EN bit in DMA\_SxCR register is reset to 0 by the software to stop the stream before the last data hardware signal (single or burst) is sent by the peripheral. In such a case, the stream is switched off and the FIFO flush is triggered in the case of a peripheral-to-memory DMA transfer. The TCIFx flag of the corresponding stream is set in the status register to indicate the DMA completion. To know the number of data items transferred during the DMA transfer, read the DMA\_SxNDTR register and apply the following formula:
  - $\text{Number\_of\_data\_transferred} = 0xFFFF - \text{DMA\_SxNDTR}$
- Normal stream interruption due to the reception of a last data hardware signal: the stream is automatically interrupted when the peripheral requests the last transfer (single or burst) and when this transfer is complete. the TCIFx flag of the corresponding stream is set in the status register to indicate the DMA transfer completion. To know the number of data items transferred, read the DMA\_SxNDTR register and apply the same formula as above.
- The DMA\_SxNDTR register reaches 0: the TCIFx flag of the corresponding stream is set in the status register to indicate the forced DMA transfer completion. The stream is automatically switched off even though the last data hardware signal (single or burst) has not been yet asserted. The already transferred data will not be lost. This means that a maximum of 65535 data items can be managed by the DMA in a single transaction, even in peripheral flow control mode.

*Note:* When configured in memory-to-memory mode, the DMA is always the flow controller and the PFCTRL bit is forced to 0 by hardware.

*The Circular mode is forbidden in the peripheral flow controller mode.*

### 9.3.16 Summary of the possible DMA configurations

Table 35 summarizes the different possible DMA configurations.

**Table 35. Possible DMA configurations**

DMA transfer mode	Source	Destination	Flow controller	Circular mode	Transfer type	Direct mode	Double buffer mode
Peripheral-to-memory	AHB peripheral port	AHB memory port	DMA	possible	single	possible	possible
					burst	forbidden	
			Peripheral	forbidden	single	possible	forbidden
					burst	forbidden	
Memory-to-peripheral	AHB memory port	AHB peripheral port	DMA	possible	single	possible	possible
					burst	forbidden	
			Peripheral	forbidden	single	possible	forbidden
					burst	forbidden	
Memory-to-memory	AHB peripheral port	AHB memory port	DMA only	forbidden	single	forbidden	forbidden
					burst		

### 9.3.17 Stream configuration procedure

The following sequence should be followed to configure a DMA stream x (where x is the stream number):

1. If the stream is enabled, disable it by resetting the EN bit in the DMA\_SxCR register, then read this bit in order to confirm that there is no ongoing stream operation. Writing this bit to 0 is not immediately effective since it is actually written to 0 once all the current transfers have finished. When the EN bit is read as 0, this means that the stream is ready to be configured. It is therefore necessary to wait for the EN bit to be cleared before starting any stream configuration. All the stream dedicated bits set in the status register (DMA\_LISR and DMA\_HISR) from the previous data block DMA transfer should be cleared before the stream can be re-enabled.
2. Set the peripheral port register address in the DMA\_SxPAR register. The data will be moved from/ to this address to/ from the peripheral port after the peripheral event.
3. Set the memory address in the DMA\_SxMA0R register (and in the DMA\_SxMA1R register in the case of a double buffer mode). The data will be written to or read from this memory after the peripheral event.
4. Configure the total number of data items to be transferred in the DMA\_SxNDTR register. After each peripheral event or each beat of the burst, this value is decremented.
5. Select the DMA channel (request) using CHSEL[2:0] in the DMA\_SxCR register.
6. If the peripheral is intended to be the flow controller and if it supports this feature, set the PFCTRL bit in the DMA\_SxCR register.
7. Configure the stream priority using the PL[1:0] bits in the DMA\_SxCR register.
8. Configure the FIFO usage (enable or disable, threshold in transmission and reception)
9. Configure the data transfer direction, peripheral and memory incremented/fixed mode, single or burst transactions, peripheral and memory data widths, Circular mode,

Double buffer mode and interrupts after half and/or full transfer, and/or errors in the DMA\_SxCR register.

10. Activate the stream by setting the EN bit in the DMA\_SxCR register.

As soon as the stream is enabled, it can serve any DMA request from the peripheral connected to the stream.

Once half the data have been transferred on the AHB destination port, the half-transfer flag (HTIF) is set and an interrupt is generated if the half-transfer interrupt enable bit (HTIE) is set. At the end of the transfer, the transfer complete flag (TCIF) is set and an interrupt is generated if the transfer complete interrupt enable bit (TCIE) is set.

---

**Warning:** To switch off a peripheral connected to a DMA stream request, it is mandatory to, first, switch off the DMA stream to which the peripheral is connected, then to wait for EN bit = 0. Only then can the peripheral be safely disabled.

---

### 9.3.18 Error management

The DMA controller can detect the following errors:

- **Transfer error:** the transfer error interrupt flag (TEIFx) is set when:
  - A bus error occurs during a DMA read or a write access
  - A write access is requested by software on a memory address register in Double buffer mode whereas the stream is enabled and the current target memory is the one impacted by the write into the memory address register (refer to [Section 9.3.9: Double buffer mode](#))
- **FIFO error:** the FIFO error interrupt flag (FEIFx) is set if:
  - A FIFO underrun condition is detected
  - A FIFO overrun condition is detected (no detection in memory-to-memory mode because requests and transfers are internally managed by the DMA)
  - The stream is enabled while the FIFO threshold level is not compatible with the size of the memory burst (refer to [Table 34: FIFO threshold configurations](#))
- **Direct mode error:** the direct mode error interrupt flag (DMEIFx) can only be set in the peripheral-to-memory mode while operating in direct mode and when the MINC bit in the DMA\_SxCR register is cleared. This flag is set when a DMA request occurs while the previous data have not yet been fully transferred into the memory (because the memory bus was not granted). In this case, the flag indicates that 2 data items were be transferred successively to the same destination address, which could be an issue if the destination is not able to manage this situation

In direct mode, the FIFO error flag can also be set under the following conditions:

- In the peripheral-to-memory mode, the FIFO can be saturated (overrun) if the memory bus is not granted for several peripheral requests
- In the memory-to-peripheral mode, an underrun condition may occur if the memory bus has not been granted before a peripheral request occurs

If the TEIFx or the FEIFx flag is set due to incompatibility between burst size and FIFO threshold level, the faulty stream is automatically disabled through a hardware clear of its EN bit in the corresponding stream configuration register (DMA\_SxCR).

If the DMEIFx or the FEIFx flag is set due to an overrun or underrun condition, the faulty stream is not automatically disabled and it is up to the software to disable or not the stream by resetting the EN bit in the DMA\_SxCR register. This is because there is no data loss when this kind of errors occur.

When the stream's error interrupt flag (TEIF, FEIF, DMEIF) in the DMA\_LISR or DMA\_HISR register is set, an interrupt is generated if the corresponding interrupt enable bit (TEIE, FEIE, DMIE) in the DMA\_SxCR or DMA\_SxFCR register is set.

*Note:* When a FIFO overrun or underrun condition occurs, the data are not lost because the peripheral request is not acknowledged by the stream until the overrun or underrun condition is cleared. If this acknowledge takes too much time, the peripheral itself may detect an overrun or underrun condition of its internal buffer and data might be lost.

## 9.4 DMA interrupts

For each DMA stream, an interrupt can be produced on the following events:

- Half-transfer reached
- Transfer complete
- Transfer error
- Fifo error (overrun, underrun or FIFO level error)
- Direct mode error

Separate interrupt enable control bits are available for flexibility as shown in [Table 36](#).

**Table 36. DMA interrupt requests**

Interrupt event	Event flag	Enable control bit
Half-transfer	HTIF	HTIE
Transfer complete	TCIF	TCIE
Transfer error	TEIF	TEIE
FIFO overrun/underrun	FEIF	FEIE
Direct mode error	DMEIF	DMEIE

*Note:* Before setting an Enable control bit to '1', the corresponding event flag should be cleared, otherwise an interrupt is immediately generated.

## 9.5 DMA registers

The DMA registers have to be accessed by words (32 bits).

### 9.5.1 DMA low interrupt status register (DMA\_LISR)

Address offset: 0x00

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved				TCIF3	HTIF3	TEIF3	DMEIF3	Reserv ed	FEIF3	TCIF2	HTIF2	TEIF2	DMEIF2	Reserv ed	FEIF2
r	r	r	r	r	r	r	r		r	r	r	r	r		r
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved				TCIF1	HTIF1	TEIF1	DMEIF1	Reserv ed	FEIF1	TCIF0	HTIF0	TEIF0	DMEIF0	Reserv ed	FEIF0
r	r	r	r	r	r	r	r		r	r	r	r	r		r

Bits 31:28, 15:12 Reserved, must be kept at reset value.

Bits 27, 21, 11, 5 **TCIFx**: Stream x transfer complete interrupt flag (x = 3..0)

This bit is set by hardware. It is cleared by software writing 1 to the corresponding bit in the DMA\_LIFCR register.

0: No transfer complete event on stream x

1: A transfer complete event occurred on stream x

Bits 26, 20, 10, 4 **HTIFx**: Stream x half transfer interrupt flag (x=3..0)

This bit is set by hardware. It is cleared by software writing 1 to the corresponding bit in the DMA\_LIFCR register.

0: No half transfer event on stream x

1: A half transfer event occurred on stream x

Bits 25, 19, 9, 3 **TEIFx**: Stream x transfer error interrupt flag (x=3..0)

This bit is set by hardware. It is cleared by software writing 1 to the corresponding bit in the DMA\_LIFCR register.

0: No transfer error on stream x

1: A transfer error occurred on stream x

Bits 24, 18, 8, 2 **DMEIFx**: Stream x direct mode error interrupt flag (x=3..0)

This bit is set by hardware. It is cleared by software writing 1 to the corresponding bit in the DMA\_LIFCR register.

0: No Direct Mode Error on stream x

1: A Direct Mode Error occurred on stream x

Bits 23, 17, 7, 1 Reserved, must be kept at reset value.

Bits 22, 16, 6, 0 **FEIFx**: Stream x FIFO error interrupt flag (x=3..0)

This bit is set by hardware. It is cleared by software writing 1 to the corresponding bit in the DMA\_LIFCR register.

0: No FIFO Error event on stream x

1: A FIFO Error event occurred on stream x



### 9.5.2 DMA high interrupt status register (DMA\_HISR)

Address offset: 0x04

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved				TCIF7	HTIF7	TEIF7	DMEIF7	Reserv ed	FEIF7	TCIF6	HTIF6	TEIF6	DMEIF6	Reserv ed	FEIF6
				r	r	r	r		r	r	r	r	r		r
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved				TCIF5	HTIF5	TEIF5	DMEIF5	Reserv ed	FEIF5	TCIF4	HTIF4	TEIF4	DMEIF4	Reserv ed	FEIF4
				r	r	r	r		r	r	r	r	r		r

Bits 31:28, 15:12 Reserved, must be kept at reset value.

Bits 27, 21, 11, 5 **TCIFx**: Stream x transfer complete interrupt flag (x=7..4)

This bit is set by hardware. It is cleared by software writing 1 to the corresponding bit in the DMA\_HIFCR register.

0: No transfer complete event on stream x

1: A transfer complete event occurred on stream x

Bits 26, 20, 10, 4 **HTIFx**: Stream x half transfer interrupt flag (x=7..4)

This bit is set by hardware. It is cleared by software writing 1 to the corresponding bit in the DMA\_HIFCR register.

0: No half transfer event on stream x

1: A half transfer event occurred on stream x

Bits 25, 19, 9, 3 **TEIFx**: Stream x transfer error interrupt flag (x=7..4)

This bit is set by hardware. It is cleared by software writing 1 to the corresponding bit in the DMA\_HIFCR register.

0: No transfer error on stream x

1: A transfer error occurred on stream x

Bits 24, 18, 8, 2 **DMEIFx**: Stream x direct mode error interrupt flag (x=7..4)

This bit is set by hardware. It is cleared by software writing 1 to the corresponding bit in the DMA\_HIFCR register.

0: No Direct mode error on stream x

1: A Direct mode error occurred on stream x

Bits 23, 17, 7, 1 Reserved, must be kept at reset value.

Bits 22, 16, 6, 0 **FEIFx**: Stream x FIFO error interrupt flag (x=7..4)

This bit is set by hardware. It is cleared by software writing 1 to the corresponding bit in the DMA\_HIFCR register.

0: No FIFO error event on stream x

1: A FIFO error event occurred on stream x

### 9.5.3 DMA low interrupt flag clear register (DMA\_LIFCR)

Address offset: 0x08

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved				CTCIF3	CHTIF3	CTEIF3	CDMEIF3	Reserved	CFEIF3	CTCIF2	CHTIF2	CTEIF2	CDMEIF2	Reserved	CFEIF2
				w	w	w	w		w	w	w	w	w		w
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved				CTCIF1	CHTIF1	CTEIF1	CDMEIF1	Reserved	CFEIF1	CTCIF0	CHTIF0	CTEIF0	CDMEIF0	Reserved	CFEIF0
				w	w	w	w		w	w	w	w	w		w

Bits 31:28, 15:12 Reserved, must be kept at reset value.

Bits 27, 21, 11, 5 **CTCIFx**: Stream x clear transfer complete interrupt flag (x = 3..0)  
 Writing 1 to this bit clears the corresponding TCIFx flag in the DMA\_LISR register

Bits 26, 20, 10, 4 **CHTIFx**: Stream x clear half transfer interrupt flag (x = 3..0)  
 Writing 1 to this bit clears the corresponding HTIFx flag in the DMA\_LISR register

Bits 25, 19, 9, 3 **CTEIFx**: Stream x clear transfer error interrupt flag (x = 3..0)  
 Writing 1 to this bit clears the corresponding TEIFx flag in the DMA\_LISR register

Bits 24, 18, 8, 2 **CDMEIFx**: Stream x clear direct mode error interrupt flag (x = 3..0)  
 Writing 1 to this bit clears the corresponding DMEIFx flag in the DMA\_LISR register

Bits 23, 17, 7, 1 Reserved, must be kept at reset value.

Bits 22, 16, 6, 0 **CFEIFx**: Stream x clear FIFO error interrupt flag (x = 3..0)  
 Writing 1 to this bit clears the corresponding CFEIFx flag in the DMA\_LISR register

### 9.5.4 DMA high interrupt flag clear register (DMA\_HIFCR)

Address offset: 0x0C

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved				CTCIF7	CHTIF7	CTEIF7	CDMEIF7	Reserved	CFEIF7	CTCIF6	CHTIF6	CTEIF6	CDMEIF6	Reserved	CFEIF6
				w	w	w	w		w	w	w	w	w		w
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved				CTCIF5	CHTIF5	CTEIF5	CDMEIF5	Reserved	CFEIF5	CTCIF4	CHTIF4	CTEIF4	CDMEIF4	Reserved	CFEIF4
				w	w	w	w		w	w	w	w	w		w

Bits 31:28, 15:12 Reserved, must be kept at reset value.

Bits 27, 21, 11, 5 **CTCIFx**: Stream x clear transfer complete interrupt flag (x = 7..4)  
 Writing 1 to this bit clears the corresponding TCIFx flag in the DMA\_HISR register

Bits 26, 20, 10, 4 **CHTIFx**: Stream x clear half transfer interrupt flag (x = 7..4)  
 Writing 1 to this bit clears the corresponding HTIFx flag in the DMA\_HISR register

Bits 25, 19, 9, 3 **CTEIFx**: Stream x clear transfer error interrupt flag (x = 7..4)  
 Writing 1 to this bit clears the corresponding TEIFx flag in the DMA\_HISR register



Bits 24, 18, 8, 2 **CDMEIFx**: Stream x clear direct mode error interrupt flag (x = 7..4)  
 Writing 1 to this bit clears the corresponding DMEIFx flag in the DMA\_HISR register

Bits 23, 17, 7, 1 Reserved, must be kept at reset value.

Bits 22, 16, 6, 0 **CFEIFx**: Stream x clear FIFO error interrupt flag (x = 7..4)  
 Writing 1 to this bit clears the corresponding CFEIFx flag in the DMA\_HISR register

### 9.5.5 DMA stream x configuration register (DMA\_SxCR) (x = 0..7)

This register is used to configure the concerned stream.

Address offset: 0x10 + 0x18 × *stream number*

Reset value: 0x0000 0000

Reserved				CHSEL[3:0]			MBURST [1:0]		PBURST[1:0]		Reserved	CT	DBM or reserved	PL[1:0]	
				rw	rw	rw	rw	rw	rw	rw		rw	rw or r	rw	rw
31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved				CHSEL[3:0]			MBURST [1:0]		PBURST[1:0]		Reserved	CT	DBM or reserved	PL[1:0]	
				rw	rw	rw	rw	rw	rw	rw		rw	rw or r	rw	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
PINCOS	MSIZE[1:0]		PSIZE[1:0]		MINC	PINC	CIRC	DIR[1:0]		PFCTRL	TCIE	HTIE	TEIE	DMEIE	EN
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 31:28 Reserved, must be kept at reset value.

Bits 27:25 **CHSEL[2:0]**: Channel selection

These bits are set and cleared by software.

- 000: channel 0 selected
- 001: channel 1 selected
- 010: channel 2 selected
- 011: channel 3 selected
- 100: channel 4 selected
- 101: channel 5 selected
- 110: channel 6 selected
- 111: channel 7 selected

These bits are protected and can be written only if EN is '0'

Bits 24:23 **MBURST**: Memory burst transfer configuration

These bits are set and cleared by software.

- 00: single transfer
- 01: INCR4 (incremental burst of 4 beats)
- 10: INCR8 (incremental burst of 8 beats)
- 11: INCR16 (incremental burst of 16 beats)

These bits are protected and can be written only if EN is '0'

In direct mode, these bits are forced to 0x0 by hardware as soon as bit EN= '1'.

Bits 22:21 **PBURST[1:0]**: Peripheral burst transfer configuration

These bits are set and cleared by software.

- 00: single transfer
- 01: INCR4 (incremental burst of 4 beats)
- 10: INCR8 (incremental burst of 8 beats)
- 11: INCR16 (incremental burst of 16 beats)

These bits are protected and can be written only if EN is '0'

In direct mode, these bits are forced to 0x0 by hardware.

- Bit 20 Reserved, must be kept at reset value.
- Bit 19 **CT**: Current target (only in double buffer mode)  
This bits is set and cleared by hardware. It can also be written by software.  
0: The current target memory is Memory 0 (addressed by the DMA\_SxM0AR pointer)  
1: The current target memory is Memory 1 (addressed by the DMA\_SxM1AR pointer)  
This bit can be written only if EN is '0' to indicate the target memory area of the first transfer.  
Once the stream is enabled, this bit operates as a status flag indicating which memory area is the current target.
- Bit 18 **DBM**: Double buffer mode  
This bits is set and cleared by software.  
0: No buffer switching at the end of transfer  
1: Memory target switched at the end of the DMA transfer  
This bit is protected and can be written only if EN is '0'.
- Bits 17:16 **PL[1:0]**: Priority level  
These bits are set and cleared by software.  
00: Low  
01: Medium  
10: High  
11: Very high  
These bits are protected and can be written only if EN is '0'.
- Bit 15 **PINCOS**: Peripheral increment offset size  
This bit is set and cleared by software  
0: The offset size for the peripheral address calculation is linked to the PSIZE  
1: The offset size for the peripheral address calculation is fixed to 4 (32-bit alignment).  
This bit has no meaning if bit PINC = '0'.  
This bit is protected and can be written only if EN = '0'.  
This bit is forced low by hardware when the stream is enabled (bit EN = '1') if the direct mode is selected or if PBURST are different from "00".
- Bits 14:13 **MSIZE[1:0]**: Memory data size  
These bits are set and cleared by software.  
00: byte (8-bit)  
01: half-word (16-bit)  
10: word (32-bit)  
11: reserved  
These bits are protected and can be written only if EN is '0'.  
In direct mode, MSIZE is forced by hardware to the same value as PSIZE as soon as bit EN = '1'.
- Bits 12:11 **PSIZE[1:0]**: Peripheral data size  
These bits are set and cleared by software.  
00: Byte (8-bit)  
01: Half-word (16-bit)  
10: Word (32-bit)  
11: reserved  
These bits are protected and can be written only if EN is '0'
- Bit 10 **MINC**: Memory increment mode  
This bit is set and cleared by software.  
0: Memory address pointer is fixed  
1: Memory address pointer is incremented after each data transfer (increment is done according to MSIZE)  
This bit is protected and can be written only if EN is '0'.

- Bit 9 **PINC**: Peripheral increment mode  
This bit is set and cleared by software.  
0: Peripheral address pointer is fixed  
1: Peripheral address pointer is incremented after each data transfer (increment is done according to PSIZE)  
This bit is protected and can be written only if EN is '0'.
- Bit 8 **CIRC**: Circular mode  
This bit is set and cleared by software and can be cleared by hardware.  
0: Circular mode disabled  
1: Circular mode enabled  
When the peripheral is the flow controller (bit PFCTRL=1) and the stream is enabled (bit EN=1), then this bit is automatically forced by hardware to 0.  
It is automatically forced by hardware to 1 if the DBM bit is set, as soon as the stream is enabled (bit EN = '1').
- Bits 7:6 **DIR[1:0]**: Data transfer direction  
These bits are set and cleared by software.  
00: Peripheral-to-memory  
01: Memory-to-peripheral  
10: Memory-to-memory  
11: reserved  
These bits are protected and can be written only if EN is '0'.
- Bit 5 **PFCTRL**: Peripheral flow controller  
This bit is set and cleared by software.  
0: The DMA is the flow controller  
1: The peripheral is the flow controller  
This bit is protected and can be written only if EN is '0'.  
When the memory-to-memory mode is selected (bits DIR[1:0]=10), then this bit is automatically forced to 0 by hardware.
- Bit 4 **TCIE**: Transfer complete interrupt enable  
This bit is set and cleared by software.  
0: TC interrupt disabled  
1: TC interrupt enabled
- Bit 3 **HTIE**: Half transfer interrupt enable  
This bit is set and cleared by software.  
0: HT interrupt disabled  
1: HT interrupt enabled
- Bit 2 **TEIE**: Transfer error interrupt enable  
This bit is set and cleared by software.  
0: TE interrupt disabled  
1: TE interrupt enabled
- Bit 1 **DMEIE**: Direct mode error interrupt enable  
This bit is set and cleared by software.  
0: DME interrupt disabled  
1: DME interrupt enabled

Bit 0 **EN**: Stream enable / flag stream ready when read low

This bit is set and cleared by software.

0: Stream disabled

1: Stream enabled

This bit may be cleared by hardware:

- on a DMA end of transfer (stream ready to be configured)
- if a transfer error occurs on the AHB master buses
- when the FIFO threshold on memory AHB port is not compatible with the size of the burst

When this bit is read as 0, the software is allowed to program the Configuration and FIFO bits registers. It is forbidden to write these registers when the EN bit is read as 1.

*Note: Before setting EN bit to '1' to start a new transfer, the event flags corresponding to the stream in DMA\_LISR or DMA\_HISR register must be cleared.*

### 9.5.6 DMA stream x number of data register (DMA\_SxNDTR) (x = 0..7)

Address offset: 0x14 + 0x18 x *stream number*

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved															
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
NDT[15:0]															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 31:16 Reserved, must be kept at reset value.

Bits 15:0 **NDT[15:0]**: Number of data items to transfer

Number of data items to be transferred (0 up to 65535). This register can be written only when the stream is disabled. When the stream is enabled, this register is read-only, indicating the remaining data items to be transmitted. This register decrements after each DMA transfer.

Once the transfer has completed, this register can either stay at zero (when the stream is in normal mode) or be reloaded automatically with the previously programmed value in the following cases:

- when the stream is configured in Circular mode.
- when the stream is enabled again by setting EN bit to '1'

If the value of this register is zero, no transaction can be served even if the stream is enabled.

### 9.5.7 DMA stream x peripheral address register (DMA\_SxPAR) (x = 0..7)

Address offset:  $0x18 + 0x18 \times \text{stream number}$

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
PAR[31:16]															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
PAR[15:0]															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 31:0 **PAR[31:0]**: Peripheral address

Base address of the peripheral data register from/to which the data will be read/written.

These bits are write-protected and can be written only when bit EN = '0' in the DMA\_SxCR register.

### 9.5.8 DMA stream x memory 0 address register (DMA\_SxM0AR) (x = 0..7)

Address offset:  $0x1C + 0x18 \times \text{stream number}$

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
M0A[31:16]															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
M0A[15:0]															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 31:0 **M0A[31:0]**: Memory 0 address

Base address of Memory area 0 from/to which the data will be read/written.

These bits are write-protected. They can be written only if:

- the stream is disabled (bit EN= '0' in the DMA\_SxCR register) or
- the stream is enabled (EN='1' in DMA\_SxCR register) and bit CT = '1' in the DMA\_SxCR register (in Double buffer mode).

### 9.5.9 DMA stream x memory 1 address register (DMA\_SxM1AR) (x = 0..7)

Address offset:  $0x20 + 0x18 \times \text{stream number}$

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
M1A[31:16]															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
M1A[15:0]															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 31:0 **M1A[31:0]**: Memory 1 address (used in case of Double buffer mode)

Base address of Memory area 1 from/to which the data will be read/written.

This register is used only for the Double buffer mode.

These bits are write-protected. They can be written only if:

- the stream is disabled (bit EN= '0' in the DMA\_SxCR register) or
- the stream is enabled (EN='1' in DMA\_SxCR register) and bit CT = '0' in the DMA\_SxCR register.

### 9.5.10 DMA stream x FIFO control register (DMA\_SxFCR) (x = 0..7)

Address offset:  $0x24 + 0x24 \times stream\ number$

Reset value: 0x0000 0021

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved															
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved								FEIE	Reser ved	FS[2:0]			DMDIS	FTH[1:0]	
								rw		r	r	r	rw	rw	rw

Bits 31:8 Reserved, must be kept at reset value.

Bit 7 **FEIE**: FIFO error interrupt enable

This bit is set and cleared by software.

0: FE interrupt disabled

1: FE interrupt enabled

Bit 6 Reserved, must be kept at reset value.



Bits 5:3 **FS[2:0]**: FIFO status

These bits are read-only.

000:  $0 < \text{fifo\_level} < 1/4$

001:  $1/4 \leq \text{fifo\_level} < 1/2$

010:  $1/2 \leq \text{fifo\_level} < 3/4$

011:  $3/4 \leq \text{fifo\_level} < \text{full}$

100: FIFO is empty

101: FIFO is full

others: no meaning

These bits are not relevant in the direct mode (DMDIS bit is zero).

Bit 2 **DMDIS**: Direct mode disable

This bit is set and cleared by software. It can be set by hardware.

0: Direct mode enabled

1: Direct mode disabled

This bit is protected and can be written only if EN is '0'.

This bit is set by hardware if the memory-to-memory mode is selected (DIR bit in DMA\_SxCR are "10") and the EN bit in the DMA\_SxCR register is '1' because the direct mode is not allowed in the memory-to-memory configuration.

Bits 1:0 **FTH[1:0]**: FIFO threshold selection

These bits are set and cleared by software.

00: 1/4 full FIFO

01: 1/2 full FIFO

10: 3/4 full FIFO

11: full FIFO

These bits are not used in the direct mode when the DMIS value is zero.

These bits are protected and can be written only if EN is '0'.

### 9.5.11 DMA register map

Table 37 summarizes the DMA registers.

**Table 37. DMA register map and reset values**

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0																			
0x0000	DMA_LISR	Reserved				TCIF3	HTIF3	TEIF3	DMEIF3	Reserved	FEIF3	TCIF2	HTIF2	TEIF2	DMEIF2	Reserved	FEIF2	Reserved				TCIF1	HTIF1	TEIF1	DMEIF1	Reserved	FEIF1	TCIF0	HTIF0	TEIF0	DMEIF0	Reserved	FEIF0																			
	Reset value					0	0	0	0	0	0	0	0	0	0	0	0	0					0	0	0	0	0	0	0	0	0	0	0	0																		
0x0004	DMA_HISR	Reserved				TCIF7	HTIF7	TEIF7	DMEIF7	Reserved	FEIF7	TCIF6	HTIF6	TEIF6	DMEIF6	Reserved	FEIF6	Reserved				TCIF5	HTIF5	TEIF5	DMEIF5	Reserved	FEIF5	TCIF4	HTIF4	TEIF4	DMEIF4	Reserved	FEIF4																			
	Reset value					0	0	0	0	0	0	0	0	0	0	0	0	0					0	0	0	0	0	0	0	0	0	0	0	0																		
0x0008	DMA_LIFCR	Reserved				CTCIF3	CHTIF3	CTEIF3	CDMEIF3	Reserved	CFEIF3	CTCIF2	CHTIF2	CTEIF2	CDMEIF2	Reserved	CFEIF2	Reserved				CTCIF1	CHTIF1	CTEIF1	CDMEIF1	Reserved	CFEIF1	CTCIF0	CHTIF0	CTEIF0	CDMEIF0	Reserved	CFEIF0																			
	Reset value					0	0	0	0	0	0	0	0	0	0	0	0	0					0	0	0	0	0	0	0	0	0	0	0	0																		
0x000C	DMA_HIFCR	Reserved				CTCIF7	CHTIF7	CTEIF7	CDMEIF7	Reserved	CFEIF7	CTCIF6	CHTIF6	CTEIF6	CDMEIF6	Reserved	CFEIF6	Reserved				CTCIF5	CHTIF5	CTEIF5	CDMEIF5	Reserved	CFEIF5	CTCIF4	CHTIF4	CTEIF4	CDMEIF4	Reserved	CFEIF4																			
	Reset value					0	0	0	0	0	0	0	0	0	0	0	0	0					0	0	0	0	0	0	0	0	0	0	0	0	0																	
0x0010	DMA_S0CR	Reserved				CHSEL[2:0]		MBURST[1:0]		PBURST[1:0]		Reserved		CT	DBM	PL[1:0]	PINCOS		MSIZE[1:0]		PSIZE[1:0]		MINC	PINC	CIRC	DIR[1:0]		PFCTRL	TCIE	HTIE	TEIE	DMEIE	EN																			
	Reset value					0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0																			
0x0014	DMA_S0NDTR	Reserved															NDT[15:]																																			
	Reset value																0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0												
0x0018	DMA_S0PAR	PA[31:0]																																																		
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0																			
0x001C	DMA_S0M0AR	M0A[31:0]																																																		
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0																			
0x0020	DMA_S0M1AR	M1A[31:0]																																																		
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0																			
0x0024	DMA_S0FCR	Reserved																								FEIE	FS[2:0]		DMDIS		FTH[1:0]																					
	Reset value																									0	Reserved	1	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x0028	DMA_S1CR	Reserved				CHSEL[2:0]		MBURST[1:]		PBURST[1:0]		ACK		CT	DBM	PL[1:0]	PINCOS		MSIZE[1:0]		PSIZE[1:0]		MINC	PINC	CIRC	DIR[1:0]		PFCTRL	TCIE	HTIE	TEIE	DMEIE	EN																			
	Reset value					0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0																			
0x002C	DMA_S1NDTR	Reserved															NDT[15:]																																			
	Reset value																0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0												



Table 37. DMA register map and reset values (continued)

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0x0030	DMA_S1PAR	PA[31:0]																															
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x0034	DMA_S1M0AR	M0A[31:0]																															
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x0038	DMA_S1M1AR	M1A[31:0]																															
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x003C	DMA_S1FCR	Reserved																									FEIE	Reserved	FS[2:0]		DMDIS	FTH [1:0]	
	Reset value																										0	Reserved	1	0	0	0	0
0x0040	DMA_S2CR	Reserved		CHSEL [2:0]	MBURST[1:0]		PBURST[1:0]		ACK	CT	DBM	PL[1:0]	PINCOS	MSIZE[1:0]		PSIZE[1:0]		MINC	PINC	CIRC	DIR [1:0]	PFCTRL	TCIE	HTIE	TEIE	DMEIE	EN						
	Reset value			0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0					
0x0044	DMA_S2NDTR	Reserved													NDT[15:.]																		
	Reset value														0																		
0x0048	DMA_S2PAR	PA[31:0]																															
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x004C	DMA_S2M0AR	M0A[31:0]																															
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x0050	DMA_S2M1AR	M1A[31:0]																															
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x0054	DMA_S2FCR	Reserved																									FEIE	Reserved	FS[2:0]		DMDIS	FTH [1:0]	
	Reset value																										0	Reserved	1	0	0	0	1
0x0058	DMA_S3CR	Reserved		CHSEL[2:0]	MBURST[1:0]		PBURST[1:0]		ACK	CT	DBM	PL[1:0]	PINCOS	MSIZE[1:0]		PSIZE[1:0]		MINC	PINC	CIRC	DIR[1:0]	PFCTRL	TCIE	HTIE	TEIE	DMEIE	EN						
	Reset value			0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0					
0x005C	DMA_S3NDTR	Reserved													NDT[15:.]																		
	Reset value														0																		
0x0060	DMA_S3PAR	PA[31:0]																															
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x0064	DMA_S3M0AR	M0A[31:0]																															
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0



Table 37. DMA register map and reset values (continued)

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0x0068	DMA_S3M1AR	M1A[31:0]																															
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x006C	DMA_S3FCR	Reserved																								FEIE	Reserved	FS[2:0]		DMDIS	FTH		
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x0070	DMA_S4CR	Reserved				CHSEL[2:0]		MBURST[1:0]		PBURST[1:0]		ACK	CT	DBM	PL[1:0]	PINCOS	MSIZE[1:0]		PSIZE[1:0]		MINC	PINC	CIRC	DIR	Reserved	PFCCTRL	TCIE	HTIE	TEIE	DMEIE	EN		
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	
0x0074	DMA_S4NDTR	Reserved														NDT[15:]																	
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	
0x0078	DMA_S4PAR	PA[31:0]																															
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x007C	DMA_S4M0AR	M0A[31:0]																															
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x0080	DMA_S4M1AR	M1A[31:0]																															
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x0084	DMA_S4FCR	Reserved																								FEIE	Reserved	FS[2:0]		DMDIS	FTH		
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1
0x0088	DMA_S5CR	Reserved				CHSEL[2:0]		MBURST[1:0]		PBURST[1:0]		ACK	CT	DBM	PL[1:0]	PINCOS	MSIZE[1:0]		PSIZE[1:0]		MINC	PINC	CIRC	DIR	Reserved	PFCCTRL	TCIE	HTIE	TEIE	DMEIE	EN		
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	
0x008C	DMA_S5NDTR	Reserved														NDT[15:]																	
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	
0x0090	DMA_S5PAR	PA[31:0]																															
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x0094	DMA_S5M0AR	M0A[31:0]																															
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x0098	DMA_S5M1AR	M1A[31:0]																															
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x009C	DMA_S5FCR	Reserved																								FEIE	Reserved	FS[2:0]		DMDIS	FTH		
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1
0x00A0	DMA_S6CR	Reserved				CHSEL[2:0]		MBURST[1:0]		PBURST[1:0]		ACK	CT	DBM	PL[1:0]	PINCOS	MSIZE[1:0]		PSIZE[1:0]		MINC	PINC	CIRC	DIR	Reserved	PFCCTRL	TCIE	HTIE	TEIE	DMEIE	EN		
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	
0x00A4	DMA_S6NDTR	Reserved														NDT[15:]																	
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	
0x00A8	DMA_S6PAR	PA[31:0]																															
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Table 37. DMA register map and reset values (continued)

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
0x00AC	DMA_S6M0AR	M0A[31:0]																																
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x00B0	DMA_S6M1AR	M1A[31:0]																																
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x00B4	DMA_S6FCR	Reserved																								FEIE	Reserved	FS[2:0]		DMDIS		FTH [1:0]		
	Reset value																									0		1	0	0	0	0	0	1
0x00B8	DMA_S7CR	Reserved			CHSEL[2:0]		MBURST[1:0]		PBURST[1:0]		ACK	CT	DBM	PL[1:0]	PINCOS	MSIZE[1:0]		PSIZE[1:0]		MNC	PINC	CIRC	DIR[1:0]		PFCtrl	TCIE	HTIE	TEIE	DMEIE	EN				
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0		
0x00BC	DMA_S7NDTR	Reserved													NDT[15:]																			
	Reset value														0																			
0x00C0	DMA_S7PAR	PA[31:0]																																
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	
0x00C4	DMA_S7M0AR	M0A[31:0]																																
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	
0x00C8	DMA_S7M1AR	M1A[31:0]																																
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	
0x00CC	DMA_S7FCR	Reserved																								FEIE	Reserved	FS[2:0]		DMDIS		FTH [1:0]		
	Reset value																									0		1	0	0	0	0	0	0

Refer to [Table 1 on page 38](#) for the register boundary addresses.

## 10 Interrupts and events

### 10.1 Nested vectored interrupt controller (NVIC)

#### 10.1.1 NVIC features

The nested vector interrupt controller NVIC includes the following features:

- 52 maskable interrupt channels (not including the 16 interrupt lines of Cortex<sup>®</sup>-M4 with FPU)
- 16 programmable priority levels (4 bits of interrupt priority are used)
- low-latency exception and interrupt handling
- power management control
- implementation of system control registers

The NVIC and the processor core interface are closely coupled, which enables low latency interrupt processing and efficient processing of late arriving interrupts.

All interrupts including the core exceptions are managed by the NVIC. For more information on exceptions and NVIC programming, refer to programming manual PM0214.

#### 10.1.2 SysTick calibration value register

The SysTick calibration value is fixed to 10500, which gives a reference time base of 1 ms with the SysTick clock set to 10.5 MHz (HCLK/8, with HCLK set to 84 MHz).

#### 10.1.3 Interrupt and exception vectors

See [Table 38](#), for the vector table for the STM32F401xB/C and STM32F401xD/E devices.

### 10.2 External interrupt/event controller (EXTI)

The external interrupt/event controller consists of up to 23 edge detectors for generating event/interrupt requests. Each input line can be independently configured to select the type (interrupt or event) and the corresponding trigger event (rising or falling or both). Each line can also be masked independently. A pending register maintains the status line of the interrupt requests.

**Table 38. Vector table for STM32F401xB/CSTM32F401xD/E**

Position	Priority	Type of priority	Acronym	Description	Address
	-	-	-	Reserved	0x0000 0000
	-3	fixed	Reset	Reset	0x0000 0004

**Table 38. Vector table for STM32F401xB/CSTM32F401xD/E (continued)**

Position	Priority	Type of priority	Acronym	Description	Address
	-2	fixed	NMI	Non maskable interrupt, Clock Security System	0x0000 0008
	-1	fixed	HardFault	All class of fault	0x0000 000C
	0	settable	MemManage	Memory management	0x0000 0010
	1	settable	BusFault	Pre-fetch fault, memory access fault	0x0000 0014
	2	settable	UsageFault	Undefined instruction or illegal state	0x0000 0018
	-	-	-	Reserved	0x0000 001C - 0x0000 002B
	3	settable	SVCall	System Service call via SWI instruction	0x0000 002C
	4	settable	Debug Monitor	Debug Monitor	0x0000 0030
		-	-	Reserved	0x0000 0034
	5	settable	PendSV	Pendable request for system service	0x0000 0038
	6	settable	Systick	System tick timer	0x0000 003C
0	7	settable	WWDG	Window Watchdog interrupt	0x0000 0040
1	8	settable	EXTI16 / PVD	EXTI Line 16 interrupt / PVD through EXTI line detection interrupt	0x0000 0044
2	9	settable	EXTI21 / TAMP_STAMP	EXTI Line 21 interrupt / Tamper and TimeStamp interrupts through the EXTI line	0x0000 0048
3	10	settable	EXTI22 / RTC_WKUP	EXTI Line 22 interrupt / RTC Wakeup interrupt through the EXTI line	0x0000 004C
4	11	settable	FLASH	Flash global interrupt	0x0000 0050
5	12	settable	RCC	RCC global interrupt	0x0000 0054
6	13	settable	EXTI0	EXTI Line0 interrupt	0x0000 0058
7	14	settable	EXTI1	EXTI Line1 interrupt	0x0000 005C
8	15	settable	EXTI2	EXTI Line2 interrupt	0x0000 0060
9	16	settable	EXTI3	EXTI Line3 interrupt	0x0000 0064
10	17	settable	EXTI4	EXTI Line4 interrupt	0x0000 0068
11	18	settable	DMA1_Stream0	DMA1 Stream0 global interrupt	0x0000 006C
12	19	settable	DMA1_Stream1	DMA1 Stream1 global interrupt	0x0000 0070
13	20	settable	DMA1_Stream2	DMA1 Stream2 global interrupt	0x0000 0074
14	21	settable	DMA1_Stream3	DMA1 Stream3 global interrupt	0x0000 0078

Table 38. Vector table for STM32F401xB/CSTM32F401xD/E (continued)

Position	Priority	Type of priority	Acronym	Description	Address
15	22	settable	DMA1_Stream4	DMA1 Stream4 global interrupt	0x0000 007C
16	23	settable	DMA1_Stream5	DMA1 Stream5 global interrupt	0x0000 0080
17	24	settable	DMA1_Stream6	DMA1 Stream6 global interrupt	0x0000 0084
18	25	settable	ADC	ADC1 global interrupts	0x0000 0088
23	30	settable	EXTI9_5	EXTI Line[9:5] interrupts	0x0000 009C
24	31	settable	TIM1_BRK_TIM9	TIM1 Break interrupt and TIM9 global interrupt	0x0000 00A0
25	32	settable	TIM1_UP_TIM10	TIM1 Update interrupt and TIM10 global interrupt	0x0000 00A4
26	33	settable	TIM1_TRG_COM_TIM11	TIM1 Trigger and Commutation interrupts and TIM11 global interrupt	0x0000 00A8
27	34	settable	TIM1_CC	TIM1 Capture Compare interrupt	0x0000 00AC
28	35	settable	TIM2	TIM2 global interrupt	0x0000 00B0
29	36	settable	TIM3	TIM3 global interrupt	0x0000 00B4
30	37	settable	TIM4	TIM4 global interrupt	0x0000 00B8
31	38	settable	I2C1_EV	I <sup>2</sup> C1 event interrupt	0x0000 00BC
32	39	settable	I2C1_ER	I <sup>2</sup> C1 error interrupt	0x0000 00C0
33	40	settable	I2C2_EV	I <sup>2</sup> C2 event interrupt	0x0000 00C4
34	41	settable	I2C2_ER	I <sup>2</sup> C2 error interrupt	0x0000 00C8
35	42	settable	SPI1	SPI1 global interrupt	0x0000 00CC
36	43	settable	SPI2	SPI2 global interrupt	0x0000 00D0
37	44	settable	USART1	USART1 global interrupt	0x0000 00D4
38	45	settable	USART2	USART2 global interrupt	0x0000 00D8
40	47	settable	EXTI15_10	EXTI Line[15:10] interrupts	0x0000 00E0
41	48	settable	EXTI17 / RTC_Alarm	EXTI Line 17 interrupt / RTC Alarms (A and B) through EXTI line interrupt	0x0000 00E4
42	49	settable	EXTI18 / OTG_FS WKUP	EXTI Line 18 interrupt / USB On-The-Go FS Wakeup through EXTI line interrupt	0x0000 00E8
47	54	settable	DMA1_Stream7	DMA1 Stream7 global interrupt	0x0000 00FC
49	56	settable	SDIO	SDIO global interrupt	0x0000 0104
50	57	settable	TIM5	TIM5 global interrupt	0x0000 0108
51	58	settable	SPI3	SPI3 global interrupt	0x0000 010C



**Table 38. Vector table for STM32F401xB/CSTM32F401xD/E (continued)**

Position	Priority	Type of priority	Acronym	Description	Address
56	63	settable	DMA2_Stream0	DMA2 Stream0 global interrupt	0x0000 0120
57	64	settable	DMA2_Stream1	DMA2 Stream1 global interrupt	0x0000 0124
58	65	settable	DMA2_Stream2	DMA2 Stream2 global interrupt	0x0000 0128
59	66	settable	DMA2_Stream3	DMA2 Stream3 global interrupt	0x0000 012C
60	67	settable	DMA2_Stream4	DMA2 Stream4 global interrupt	0x0000 0130
67	74	settable	OTG_FS	USB On The Go FS global interrupt	0x0000 014C
68	75	settable	DMA2_Stream5	DMA2 Stream5 global interrupt	0x0000 0150
69	76	settable	DMA2_Stream6	DMA2 Stream6 global interrupt	0x0000 0154
70	77	settable	DMA2_Stream7	DMA2 Stream7 global interrupt	0x0000 0158
71	78	settable	USART6	USART6 global interrupt	0x0000 015C
72	79	settable	I2C3_EV	I <sup>2</sup> C3 event interrupt	0x0000 0160
73	80	settable	I2C3_ER	I <sup>2</sup> C3 error interrupt	0x0000 0164
81	88	Settable	FPU	FPU global interrupt	0x0000 0184
84	91	settable	SPI4	SPI 4 global interrupt	0x0000 0190

### 10.2.1 EXTI main features

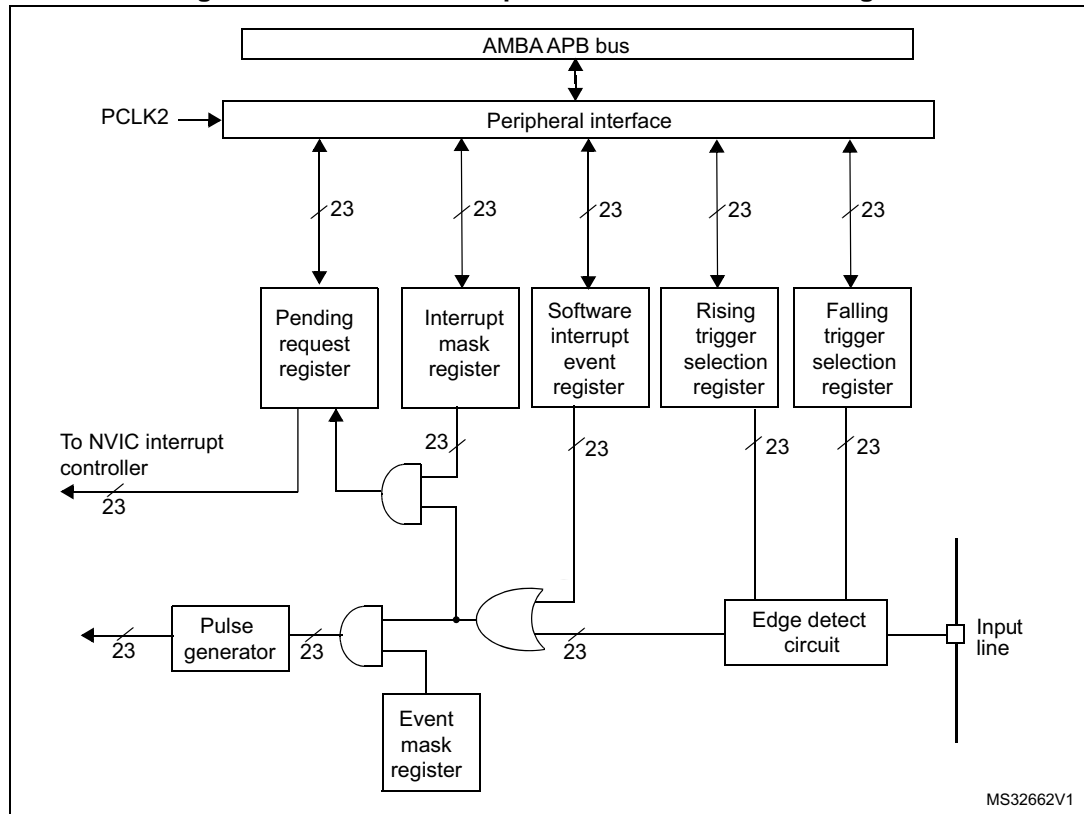
The main features of the EXTI controller are the following:

- independent trigger and mask on each interrupt/event line
- dedicated status bit for each interrupt line
- generation of up to 23 software event/interrupt requests
- detection of external signals with a pulse width lower than the APB2 clock period. Refer to the electrical characteristics section of the STM32F4xx datasheets for details on this parameter.

### 10.2.2 EXTI block diagram

Figure 29 shows the block diagram.

Figure 29. External interrupt/event controller block diagram



### 10.2.3 Wakeup event management

The STM32F4xx are able to handle external or internal events in order to wake up the core (WFE). The wakeup event can be generated either by:

- enabling an interrupt in the peripheral control register but not in the NVIC, and enabling the SEVONPEND bit in the Cortex<sup>®</sup>-M4 with FPU System Control register. When the MCU resumes from WFE, the peripheral interrupt pending bit and the peripheral NVIC IRQ channel pending bit (in the NVIC interrupt clear pending register) have to be cleared.
- or configuring an external or internal EXTI line in event mode. When the CPU resumes from WFE, it is not necessary to clear the peripheral interrupt pending bit or the NVIC IRQ channel pending bit as the pending bit corresponding to the event line is not set.

To use an external line as a wakeup event, refer to [Section 10.2.4: Functional description](#).

### 10.2.4 Functional description

To generate the interrupt, the interrupt line should be configured and enabled. This is done by programming the two trigger registers with the desired edge detection and by enabling the interrupt request by writing a '1' to the corresponding bit in the interrupt request register. When the selected edge occurs on the external interrupt line, an interrupt request is

generated. The pending bit corresponding to the interrupt line is also set. This request is reset by writing a '1' in the pending register.

To generate the event, the event line should be configured and enabled. This is done by programming the two trigger registers with the desired edge detection and by enabling the event request by writing a '1' to the corresponding bit in the event mask register. When the selected edge occurs on the event line, an event pulse is generated. The pending bit corresponding to the event line is not set.

An interrupt/event request can also be generated by software by writing a '1' in the software interrupt/event register.

### Hardware interrupt selection

To configure the 23 lines as interrupt sources, use the following procedure:

- Configure the mask bits of the 23 interrupt lines (EXTI\_IMR)
- Configure the Trigger selection bits of the interrupt lines (EXTI\_RTISR and EXTI\_FTISR)
- Configure the enable and mask bits that control the NVIC IRQ channel mapped to the external interrupt controller (EXTI) so that an interrupt coming from one of the 23 lines can be correctly acknowledged.

### Hardware event selection

To configure the 23 lines as event sources, use the following procedure:

- Configure the mask bits of the 23 event lines (EXTI\_EMR)
- Configure the Trigger selection bits of the event lines (EXTI\_RTISR and EXTI\_FTISR)

### Software interrupt/event selection

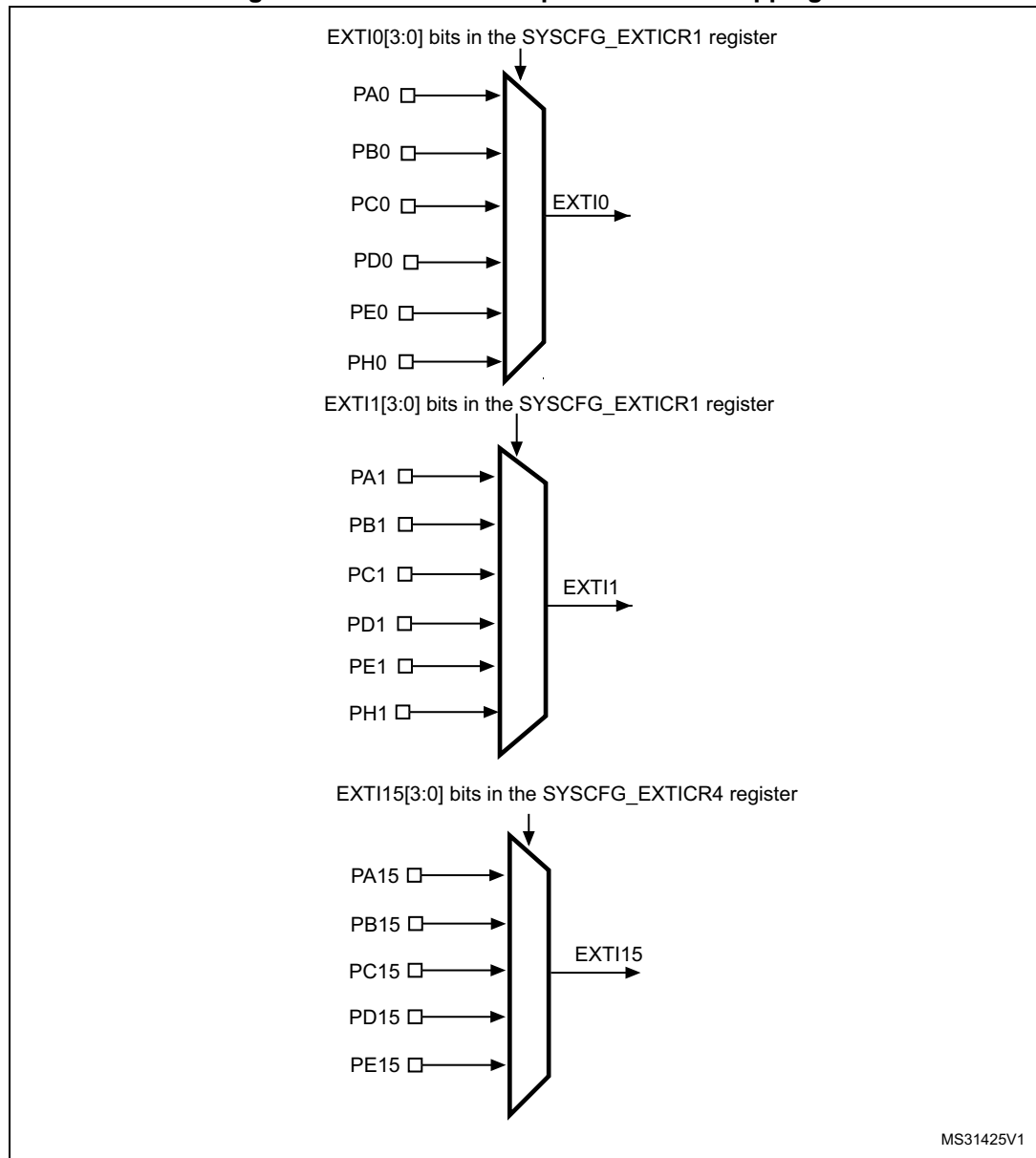
The 23 lines can be configured as software interrupt/event lines. The following is the procedure to generate a software interrupt.

- Configure the mask bits of the 23 interrupt/event lines (EXTI\_IMR, EXTI\_EMR)
- Set the required bit in the software interrupt register (EXTI\_SWIER)

### 10.2.5 External interrupt/event line mapping

Up to 81 GPIOs (STM32F401xB/C and STM32F401xD/E) are connected to the 16 external interrupt/event lines in the following manner:

**Figure 30. External interrupt/event GPIO mapping**



The five other EXTI lines are connected as follows:

- EXTI line 16 is connected to the PVD output
- EXTI line 17 is connected to the RTC Alarm event
- EXTI line 18 is connected to the USB OTG FS Wakeup event
- EXTI line 21 is connected to the RTC Tamper and TimeStamp events
- EXTI line 22 is connected to the RTC Wakeup event

### 10.3 EXTI registers

Refer to [Section 1.1 on page 34](#) for a list of abbreviations used in register descriptions.

#### 10.3.1 Interrupt mask register (EXTI\_IMR)

Address offset: 0x00

Reset value: 0x0000 0000

Reserved										MR22	MR21	Reserved			MR18	MR17	MR16
										rw	rw				rw	rw	rw
31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16		
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0		
MR15	MR14	MR13	MR12	MR11	MR10	MR9	MR8	MR7	MR6	MR5	MR4	MR3	MR2	MR1	MR0		
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw		

Bits 31:23 Reserved, must be kept at reset value.

Bits 22:0 **MRx**: Interrupt mask on line x

0: Interrupt request from line x is masked

1: Interrupt request from line x is not masked

#### 10.3.2 Event mask register (EXTI\_EMR)

Address offset: 0x04

Reset value: 0x0000 0000

Reserved										MR22	MR21	Reserved			MR18	MR17	MR16
										rw	rw				rw	rw	rw
31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16		
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0		
MR15	MR14	MR13	MR12	MR11	MR10	MR9	MR8	MR7	MR6	MR5	MR4	MR3	MR2	MR1	MR0		
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw		

Bits 31:23 Reserved, must be kept at reset value.

Bits 22:0 **MRx**: Event mask on line x

0: Event request from line x is masked

1: Event request from line x is not masked

### 10.3.3 Rising trigger selection register (EXTI\_RTSR)

Address offset: 0x08  
 Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	
Reserved									TR22	TR21	Reserved			TR18	TR17	TR16
									r/w	r/w				r/w	r/w	r/w
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
TR15	TR14	TR13	TR12	TR11	TR10	TR9	TR8	TR7	TR6	TR5	TR4	TR3	TR2	TR1	TR0	
r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	

Bits 31:23 Reserved, must be kept at reset value.

Bits 22:0 **TRx**: Rising trigger event configuration bit of line x  
 0: Rising trigger disabled (for Event and Interrupt) for input line  
 1: Rising trigger enabled (for Event and Interrupt) for input line

*Note:* The external wakeup lines are edge triggered, no glitch must be generated on these lines. If a rising edge occurs on the external interrupt line while writing to the EXTI\_RTISR register, the pending bit is be set.

Rising and falling edge triggers can be set for the same interrupt line. In this configuration, both generate a trigger condition.

### 10.3.4 Falling trigger selection register (EXTI\_FTISR)

Address offset: 0x0C  
 Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	
Reserved									TR22	TR21	Reserved			TR18	TR17	TR16
									r/w	r/w				r/w	r/w	r/w
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
TR15	TR14	TR13	TR12	TR11	TR10	TR9	TR8	TR7	TR6	TR5	TR4	TR3	TR2	TR1	TR0	
r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	

Bits 31:23 Reserved, must be kept at reset value.

Bits 22:0 **TRx**: Falling trigger event configuration bit of line x  
 0: Falling trigger disabled (for Event and Interrupt) for input line  
 1: Falling trigger enabled (for Event and Interrupt) for input line.

*Note:* The external wakeup lines are edge triggered, no glitch must be generated on these lines. If a falling edge occurs on the external interrupt line while writing to the EXTI\_FTISR register, the pending bit is not set.

Rising and falling edge triggers can be set for the same interrupt line. In this configuration, both generate a trigger condition.



### 10.3.5 Software interrupt event register (EXTI\_SWIER)

Address offset: 0x10  
 Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	
Reserved									SWIER 22	SWIER 21	Reserved			SWIER 18	SWIER 17	SWIER 16
									rw	rw				rw	rw	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
SWIER 15	SWIER 14	SWIER 13	SWIER 12	SWIER 11	SWIER 10	SWIER 9	SWIER 8	SWIER 7	SWIER 6	SWIER 5	SWIER 4	SWIER 3	SWIER 2	SWIER 1	SWIER 0	
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	

Bits 31:23 Reserved, must be kept at reset value.

Bits 22:0 **SWIERx**: Software Interrupt on line x

If interrupt are enabled on line x in the EXTI\_IMR register, writing '1' to SWIERx bit when it is set at '0' sets the corresponding pending bit in the EXTI\_PR register, thus resulting in an interrupt request generation.

This bit is cleared by clearing the corresponding bit in EXTI\_PR (by writing a 1 to the bit).

### 10.3.6 Pending register (EXTI\_PR)

Address offset: 0x14  
 Reset value: undefined

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	
Reserved									PR22	PR21	Reserved			PR18	PR17	PR16
									rc_w1	rc_w1				rc_w1	rc_w1	rc_w1
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
PR15	PR14	PR13	PR12	PR11	PR10	PR9	PR8	PR7	PR6	PR5	PR4	PR3	PR2	PR1	PR0	
rc_w1	rc_w1	rc_w1	rc_w1	rc_w1	rc_w1	rc_w1	rc_w1	rc_w1	rc_w1	rc_w1	rc_w1	rc_w1	rc_w1	rc_w1	rc_w1	

Bits 31:23 Reserved, must be kept at reset value.

Bits 22:0 **PRx**: Pending bit

0: No trigger request occurred

1: selected trigger request occurred

This bit is set when the selected edge event arrives on the external interrupt line.

This bit is cleared by programming it to '1'.

### 10.3.7 EXTI register map

Table 39 gives the EXTI register map and the reset values.

**Table 39. External interrupt/event controller register map and reset values**

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0				
0x00	<b>EXTI_IMR</b>	Reserved										MR [22:21]	Reser ved	MR[18:0]																							
	Reset value											0		0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x04	<b>EXTI_EMR</b>	Reserved										MR [22:21]	Reser ved	MR[18:0]																							
	Reset value											0		0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x08	<b>EXTI_RTSR</b>	Reserved										TR [22:21]	Reser ved	TR[18:0]																							
	Reset value											0		0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x0C	<b>EXTI_FTSR</b>	Reserved										TR [22:21]	Reser ved	TR[18:0]																							
	Reset value											0		0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x10	<b>EXTI_SWIER</b>	Reserved										SWIER [22:21]	Reser ved	SWIER[18:0]																							
	Reset value											0		0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x14	<b>EXTI_PR</b>	Reserved										PR [22:21]	Reser ved	PR[18:0]																							
	Reset value											0		0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Refer to Table 1 on page 38 for the register boundary addresses.



## 11 Analog-to-digital converter (ADC)

ADC2 and ADC3 are not available in STM32F401xB/C and STM32F401xD/E.

### 11.1 ADC introduction

The 12-bit ADC is a successive approximation analog-to-digital converter. It has up to 19 multiplexed channels allowing it to measure signals from 16 external sources, two internal sources, and the  $V_{BAT}$  channel. The A/D conversion of the channels can be performed in single, continuous, scan or discontinuous mode. The result of the ADC is stored into a left- or right-aligned 16-bit data register.

The analog watchdog feature allows the application to detect if the input voltage goes beyond the user-defined, higher or lower thresholds.

### 11.2 ADC main features

- 12-bit, 10-bit, 8-bit or 6-bit configurable resolution
- Interrupt generation at the end of conversion, end of injected conversion, and in case of analog watchdog or overrun events
- Single and continuous conversion modes
- Scan mode for automatic conversion of channel 0 to channel 'n'
- Data alignment with in-built data coherency
- Channel-wise programmable sampling time
- External trigger option with configurable polarity for both regular and injected conversions
- Discontinuous mode
- ADC supply requirements: 2.4 V to 3.6 V at full speed and down to 1.8 V at slower speed
- ADC input range:  $V_{REF-} \leq V_{IN} \leq V_{REF+}$
- DMA request generation during regular channel conversion

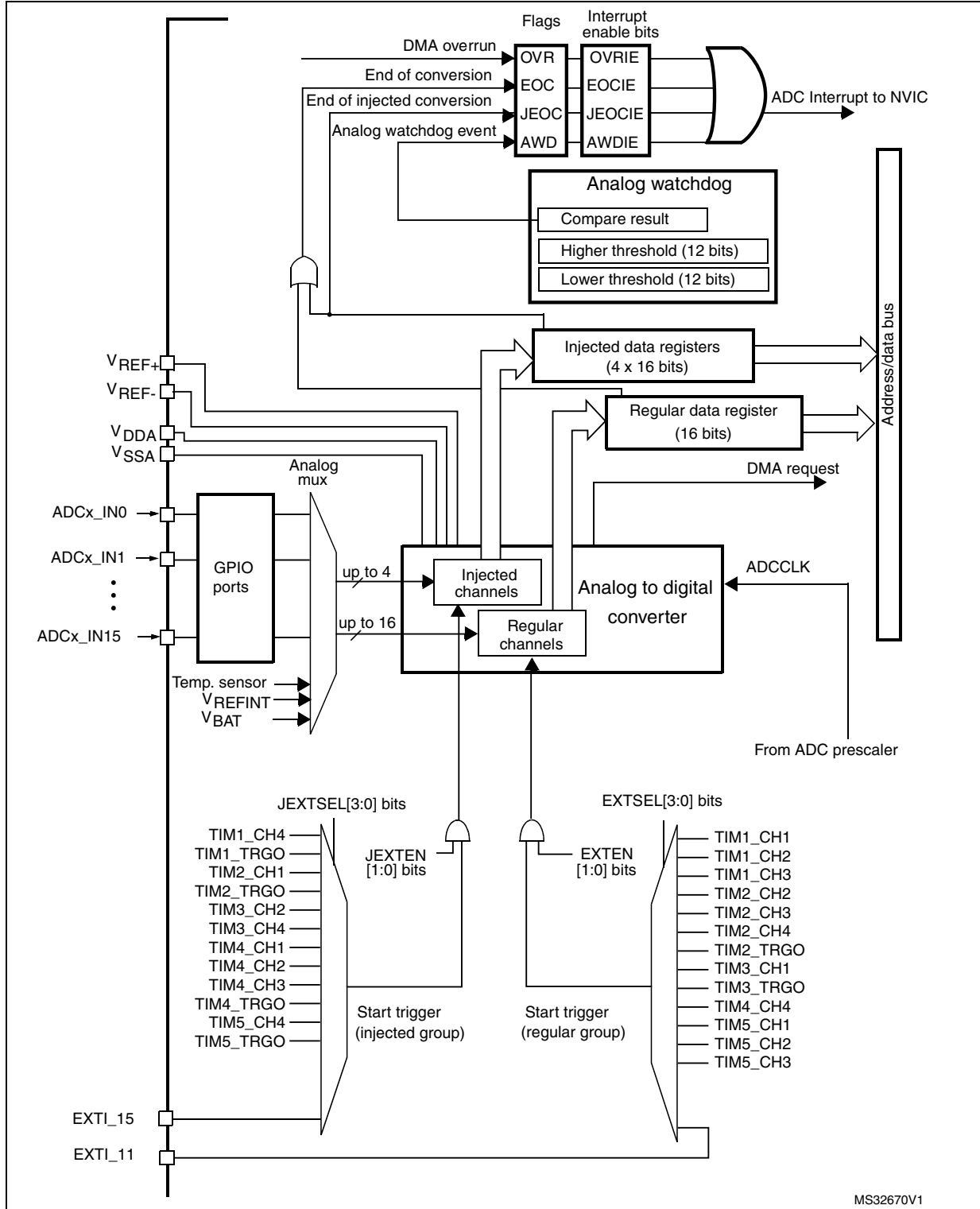
*Figure 31* shows the block diagram of the ADC.

*Note:*  $V_{REF-}$ , if available (depending on package), must be tied to  $V_{SSA}$ .

### 11.3 ADC functional description

Figure 31 shows a single ADC block diagram and Table 40 gives the ADC pin description.

Figure 31. Single ADC block diagram



MS32670V1

Table 40. ADC pins

Name	Signal type	Remarks
$V_{REF+}$	Input, analog reference positive	The higher/positive reference voltage for the ADC, $1.8\text{ V} \leq V_{REF+} \leq V_{DDA}$
$V_{DDA}$	Input, analog supply	Analog power supply equal to $V_{DD}$ and $2.4\text{ V} \leq V_{DDA} \leq V_{DD}$ (3.6 V) for full speed $1.8\text{ V} \leq V_{DDA} \leq V_{DD}$ (3.6 V) for reduced speed
$V_{REF-}$	Input, analog reference negative	The lower/negative reference voltage for the ADC, $V_{REF-} = V_{SSA}$
$V_{SSA}$	Input, analog supply ground	Ground for analog power supply equal to $V_{SS}$
ADCx_IN[15:0]	Analog input signals	16 analog input channels

### 11.3.1 ADC on-off control

The ADC is powered on by setting the ADON bit in the ADC\_CR2 register. When the ADON bit is set for the first time, it wakes up the ADC from the Power-down mode.

Conversion starts when either the SWSTART or the JSWSTART bit is set.

You can stop conversion and put the ADC in power down mode by clearing the ADON bit. In this mode the ADC consumes almost no power (only a few  $\mu\text{A}$ ).

### 11.3.2 ADC clock

The ADC features two clock schemes:

- Clock for the analog circuitry: ADCCLK  
This clock is generated from the APB2 clock divided by a programmable prescaler that allows the ADC to work at  $f_{PCLK2}/2, /4, /6$  or  $/8$ . Refer to the datasheets for the maximum value of ADCCLK.
- Clock for the digital interface (used for registers read/write access)  
This clock is equal to the APB2 clock. The digital interface clock can be enabled/disabled individually for each ADC through the RCC APB2 peripheral clock enable register (RCC\_APB2ENR).

### 11.3.3 Channel selection

There are 16 multiplexed channels. It is possible to organize the conversions in two groups: regular and injected. A group consists of a sequence of conversions that can be done on any channel and in any order. For instance, it is possible to implement the conversion sequence in the following order: ADC\_IN3, ADC\_IN8, ADC\_IN2, ADC\_IN2, ADC\_IN0, ADC\_IN2, ADC\_IN2, ADC\_IN15.

- A **regular group** is composed of up to 16 conversions. The regular channels and their order in the conversion sequence must be selected in the ADC\_SQRx registers. The total number of conversions in the regular group must be written in the L[3:0] bits in the ADC\_SQR1 register.
- An **injected group** is composed of up to 4 conversions. The injected channels and their order in the conversion sequence must be selected in the ADC\_JSQR register.

The total number of conversions in the injected group must be written in the L[1:0] bits in the ADC\_JSQR register.

If the ADC\_SQRx or ADC\_JSQR registers are modified during a conversion, the current conversion is reset and a new start pulse is sent to the ADC to convert the newly chosen group.

### Temperature sensor, V<sub>REFINT</sub> and V<sub>BAT</sub> internal channels

- The temperature sensor is internally connected to ADC1\_IN18 channel which is shared with VBAT. Only one conversion, temperature sensor or VBAT, must be selected at a time. When the temperature sensor and VBAT conversion are set simultaneously, only the VBAT conversion is performed.

The internal reference voltage VREFINT is connected to ADC1\_IN17.

The V<sub>BAT</sub> channel (connected to channel ADC1\_IN18) can also be converted as an injected or regular channel.

*Note:* The temperature sensor, V<sub>REFINT</sub> and the V<sub>BAT</sub> channel are available only on the master ADC1 peripheral.

### 11.3.4 Single conversion mode

In Single conversion mode the ADC does one conversion. This mode is started with the CONT bit at 0 by either:

- setting the SWSTART bit in the ADC\_CR2 register (for a regular channel only)
- setting the JSWSTART bit (for an injected channel)
- external trigger (for a regular or injected channel)

Once the conversion of the selected channel is complete:

- If a regular channel was converted:
  - The converted data are stored into the 16-bit ADC\_DR register
  - The EOC (end of conversion) flag is set
  - An interrupt is generated if the EOCIE bit is set
- If an injected channel was converted:
  - The converted data are stored into the 16-bit ADC\_JDR1 register
  - The JEOC (end of conversion injected) flag is set
  - An interrupt is generated if the JEOCIE bit is set

Then the ADC stops.

### 11.3.5 Continuous conversion mode

In continuous conversion mode, the ADC starts a new conversion as soon as it finishes one. This mode is started with the CONT bit at 1 either by external trigger or by setting the SWSTRT bit in the ADC\_CR2 register (for regular channels only).

After each conversion:

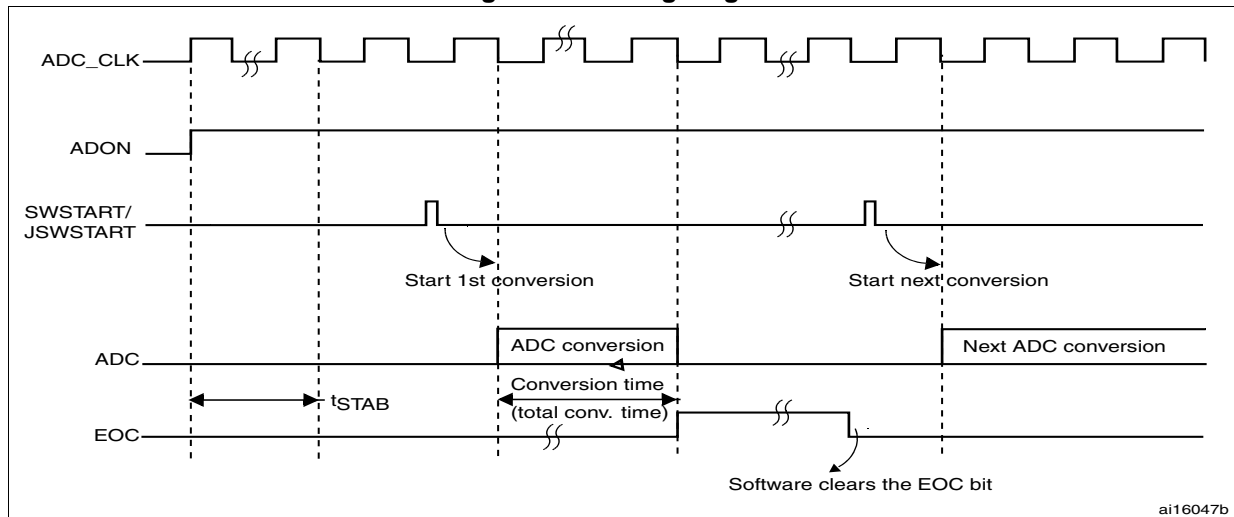
- If a regular group of channels was converted:
  - The last converted data are stored into the 16-bit ADC\_DR register
  - The EOC (end of conversion) flag is set
  - An interrupt is generated if the EOCIE bit is set

Note: *Injected channels cannot be converted continuously. The only exception is when an injected channel is configured to be converted automatically after regular channels in continuous mode (using JAUTO bit), refer to [Auto-injection](#) section).*

### 11.3.6 Timing diagram

As shown in [Figure 32](#), the ADC needs a stabilization time of  $t_{STAB}$  before it starts converting accurately. After the start of the ADC conversion and after 15 clock cycles, the EOC flag is set and the 16-bit ADC data register contains the result of the conversion.

Figure 32. Timing diagram



### 11.3.7 Analog watchdog

The AWD analog watchdog status bit is set if the analog voltage converted by the ADC is below a lower threshold or above a higher threshold. These thresholds are programmed in the 12 least significant bits of the ADC\_HTR and ADC\_LTR 16-bit registers. An interrupt can be enabled by using the AWDIE bit in the ADC\_CR1 register.

The threshold value is independent of the alignment selected by the ALIGN bit in the ADC\_CR2 register. The analog voltage is compared to the lower and higher thresholds before alignment.

[Table 41](#) shows how the ADC\_CR1 register should be configured to enable the analog watchdog on one or more channels.

Figure 33. Analog watchdog's guarded area

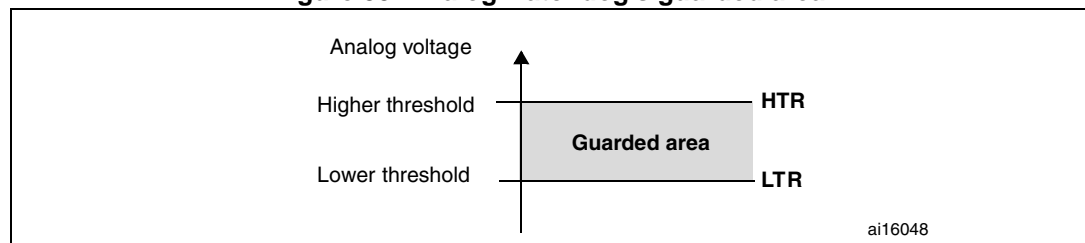


Table 41. Analog watchdog channel selection

Channels guarded by the analog watchdog	ADC_CR1 register control bits (x = don't care)		
	AWDSGL bit	AWDEN bit	JAWDEN bit
None	x	0	0
All injected channels	0	0	1
All regular channels	0	1	0
All regular and injected channels	0	1	1
Single <sup>(1)</sup> injected channel	1	0	1
Single <sup>(1)</sup> regular channel	1	1	0
Single <sup>(1)</sup> regular or injected channel	1	1	1

1. Selected by the AWDCH[4:0] bits

### 11.3.8 Scan mode

This mode is used to scan a group of analog channels.

The Scan mode is selected by setting the SCAN bit in the ADC\_CR1 register. Once this bit has been set, the ADC scans all the channels selected in the ADC\_SQRx registers (for regular channels) or in the ADC\_JSQR register (for injected channels). A single conversion is performed for each channel of the group. After each end of conversion, the next channel in the group is converted automatically. If the CONT bit is set, regular channel conversion does not stop at the last selected channel in the group but continues again from the first selected channel.

If the DMA bit is set, the direct memory access (DMA) controller is used to transfer the data converted from the regular group of channels (stored in the ADC\_DR register) to SRAM after each regular channel conversion.

The EOC bit is set in the ADC\_SR register:

- At the end of each regular group sequence if the EOCS bit is cleared to 0
- At the end of each regular channel conversion if the EOCS bit is set to 1

The data converted from an injected channel are always stored into the ADC\_JDRx registers.

### 11.3.9 Injected channel management

#### Triggered injection

To use triggered injection, the JAUTO bit must be cleared in the ADC\_CR1 register.

1. Start the conversion of a group of regular channels either by external trigger or by setting the SWSTART bit in the ADC\_CR2 register.
2. If an external injected trigger occurs or if the JSWSTART bit is set during the conversion of a regular group of channels, the current conversion is reset and the injected channel sequence switches to Scan-once mode.
3. Then, the regular conversion of the regular group of channels is resumed from the last interrupted regular conversion.  
If a regular event occurs during an injected conversion, the injected conversion is not

interrupted but the regular sequence is executed at the end of the injected sequence.  
 Figure 34 shows the corresponding timing diagram.

*Note:* When using triggered injection, one must ensure that the interval between trigger events is longer than the injection sequence. For instance, if the sequence length is 30 ADC clock cycles (that is two conversions with a sampling time of 3 clock periods), the minimum interval between triggers must be 31 ADC clock cycles.

**Auto-injection**

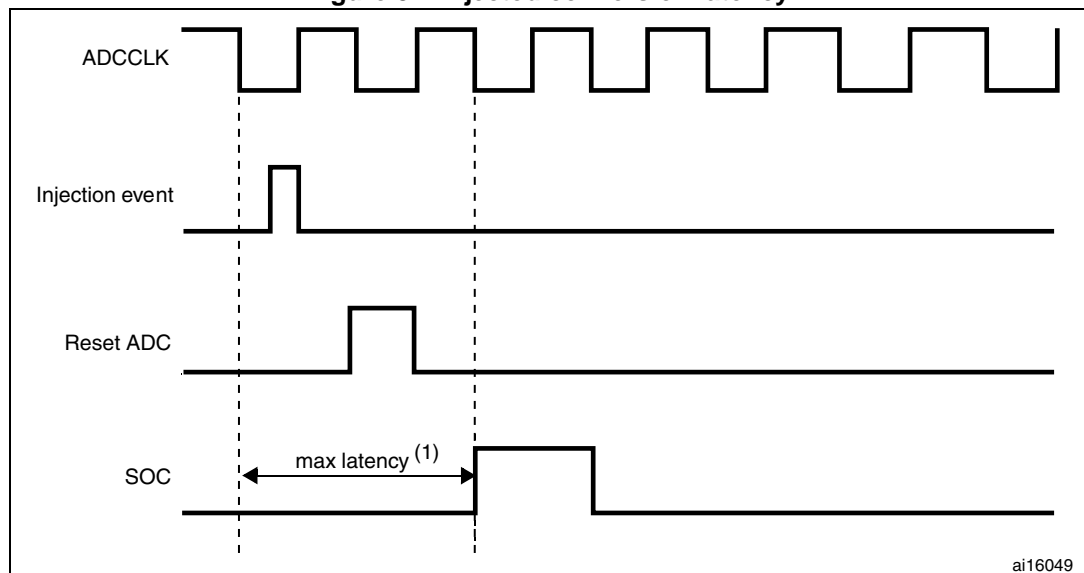
If the JAUTO bit is set, then the channels in the injected group are automatically converted after the regular group of channels. This can be used to convert a sequence of up to 20 conversions programmed in the ADC\_SQRx and ADC\_JSQR registers.

In this mode, external trigger on injected channels must be disabled.

If the CONT bit is also set in addition to the JAUTO bit, regular channels followed by injected channels are continuously converted.

*Note:* It is not possible to use both the auto-injected and discontinuous modes simultaneously.

**Figure 34. Injected conversion latency**



1. The maximum latency value can be found in the electrical characteristics of the STM32F401xB/C and STM32F401xD/E datasheets.

**11.3.10 Discontinuous mode**

**Regular group**

This mode is enabled by setting the DISCEN bit in the ADC\_CR1 register. It can be used to convert a short sequence of n conversions ( $n \leq 8$ ) that is part of the sequence of conversions selected in the ADC\_SQRx registers. The value of n is specified by writing to the DISCNUM[2:0] bits in the ADC\_CR1 register.

When an external trigger occurs, it starts the next n conversions selected in the ADC\_SQRx registers until all the conversions in the sequence are done. The total sequence length is defined by the L[3:0] bits in the ADC\_SQR1 register.

Example:

- $n = 3$ , channels to be converted = 0, 1, 2, 3, 6, 7, 9, 10
- 1st trigger: sequence converted 0, 1, 2. An EOC event is generated at each conversion.
- 2nd trigger: sequence converted 3, 6, 7. An EOC event is generated at each conversion
- 3rd trigger: sequence converted 9, 10. An EOC event is generated at each conversion
- 4th trigger: sequence converted 0, 1, 2. An EOC event is generated at each conversion

*Note:* When a regular group is converted in discontinuous mode, no rollover occurs.

*When all subgroups are converted, the next trigger starts the conversion of the first subgroup. In the example above, the 4th trigger reconverts the channels 0, 1 and 2 in the 1st subgroup.*

### Injected group

This mode is enabled by setting the JDISCEN bit in the ADC\_CR1 register. It can be used to convert the sequence selected in the ADC\_JSQR register, channel by channel, after an external trigger event.

When an external trigger occurs, it starts the next channel conversions selected in the ADC\_JSQR registers until all the conversions in the sequence are done. The total sequence length is defined by the JL[1:0] bits in the ADC\_JSQR register.

Example:

- $n = 1$ , channels to be converted = 1, 2, 3
- 1st trigger: channel 1 converted
- 2nd trigger: channel 2 converted
- 3rd trigger: channel 3 converted and JEOC event generated
- 4th trigger: channel 1

*Note:* When all injected channels are converted, the next trigger starts the conversion of the first injected channel. In the example above, the 4th trigger reconverts the 1st injected channel 1.

*It is not possible to use both the auto-injected and discontinuous modes simultaneously.*

*Discontinuous mode must not be set for regular and injected groups at the same time. Discontinuous mode must be enabled only for the conversion of one group.*



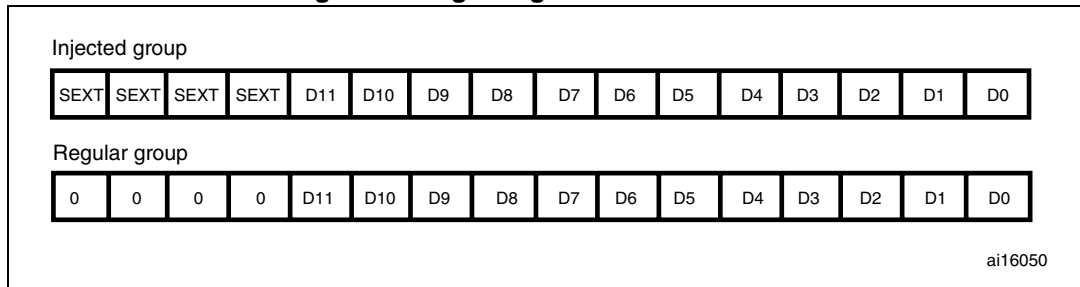
### 11.4 Data alignment

The ALIGN bit in the ADC\_CR2 register selects the alignment of the data stored after conversion. Data can be right- or left-aligned as shown in [Figure 35](#) and [Figure 36](#).

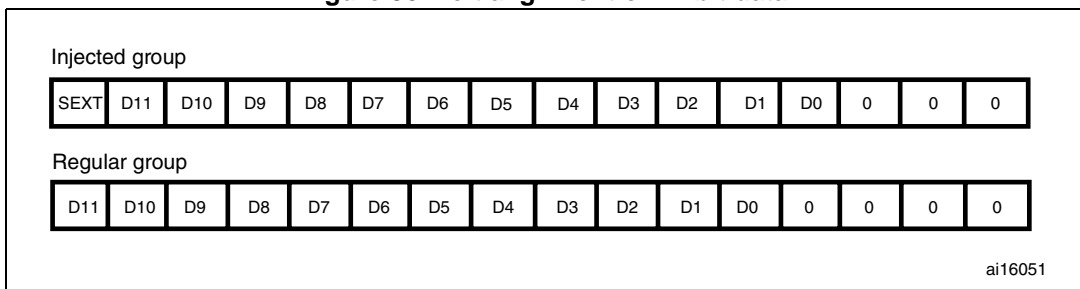
The converted data value from the injected group of channels is decreased by the user-defined offset written in the ADC\_JOFRx registers so the result can be a negative value. The SEXT bit represents the extended sign value.

For channels in a regular group, no offset is subtracted so only twelve bits are significant.

**Figure 35. Right alignment of 12-bit data**

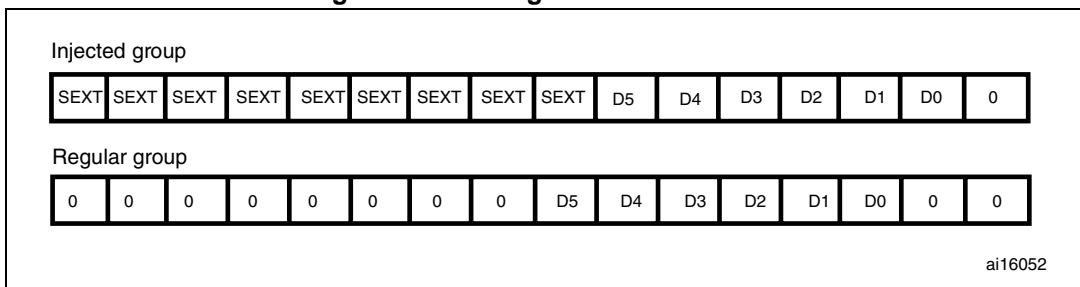


**Figure 36. Left alignment of 12-bit data**



Special case: when left-aligned, the data are aligned on a half-word basis except when the resolution is set to 6-bit. In that case, the data are aligned on a byte basis as shown in [Figure 37](#).

**Figure 37. Left alignment of 6-bit data**



## 11.5 Channel-wise programmable sampling time

The ADC samples the input voltage for a number of ADCCLK cycles that can be modified using the SMP[2:0] bits in the ADC\_SMPR1 and ADC\_SMPR2 registers. Each channel can be sampled with a different sampling time.

The total conversion time is calculated as follows:

$$T_{\text{conv}} = \text{Sampling time} + 12 \text{ cycles}$$

Example:

With ADCCLK = 30 MHz and sampling time = 3 cycles:

$$T_{\text{conv}} = 3 + 12 = 15 \text{ cycles} = 0.5 \mu\text{s with APB2 at 60 MHz}$$

## 11.6 Conversion on external trigger and trigger polarity

Conversion can be triggered by an external event (e.g. timer capture, EXTI line). If the EXTEN[1:0] control bits (for a regular conversion) or JEXTEN[1:0] bits (for an injected conversion) are different from "0b00", then external events are able to trigger a conversion with the selected polarity. [Table 42](#) provides the correspondence between the EXTEN[1:0] and JEXTEN[1:0] values and the trigger polarity.

**Table 42. Configuring the trigger polarity**

Source	EXTEN[1:0] / JEXTEN[1:0]
Trigger detection disabled	00
Detection on the rising edge	01
Detection on the falling edge	10
Detection on both the rising and falling edges	11

*Note:* The polarity of the external trigger can be changed on the fly.

The EXTSEL[3:0] and JEXTSEL[3:0] control bits are used to select which out of 16 possible events can trigger conversion for the regular and injected groups.

[Table 43](#) gives the possible external trigger for regular conversion.

Table 43. External trigger for regular channels

Source	Type	EXTSEL[3:0]
TIM1_CH1 event	Internal signal from on-chip timers	0000
TIM1_CH2 event		0001
TIM1_CH3 event		0010
TIM2_CH2 event		0011
TIM2_CH3 event		0100
TIM2_CH4 event		0101
TIM2_TRGO event		0110
TIM3_CH1 event		0111
TIM3_TRGO event		1000
TIM4_CH4 event		1001
TIM5_CH1 event		1010
TIM5_CH2 event		1011
TIM5_CH3 event		1100
Reserved		1101
Reserved		1110
EXTI line11		External pin

[Table 44](#) gives the possible external trigger for injected conversion.

Table 44. External trigger for injected channels

Source	Connection type	JEXTSEL[3:0]
TIM1_CH4 event	Internal signal from on-chip timers	0000
TIM1_TRGO event		0001
TIM2_CH1 event		0010
TIM2_TRGO event		0011
TIM3_CH2 event		0100
TIM3_CH4 event		0101
TIM4_CH1 event		0110
TIM4_CH2 event		0111
TIM4_CH3 event		1000
TIM4_TRGO event		1001
TIM5_CH4 event		1010
TIM5_TRGO event		1011
Reserved		1100
Reserved		1101
Reserved	1110	
EXTI line15	External pin	1111

Software source trigger events can be generated by setting SWSTART (for regular conversion) or JSWSTART (for injected conversion) in ADC\_CR2.

A regular group conversion can be interrupted by an injected trigger.

*Note: The trigger selection can be changed on the fly. However, when the selection changes, there is a time frame of 1 APB clock cycle during which the trigger detection is disabled. This is to avoid spurious detection during transitions.*

## 11.7 Fast conversion mode

It is possible to perform faster conversion by reducing the ADC resolution. The RES bits are used to select the number of bits available in the data register. The minimum conversion time for each resolution is then as follows:

- 12 bits:  $3 + 12 = 15$  ADCCLK cycles
- 10 bits:  $3 + 10 = 13$  ADCCLK cycles
- 8 bits:  $3 + 8 = 11$  ADCCLK cycles
- 6 bits:  $3 + 6 = 9$  ADCCLK cycles

## 11.8 Data management

### 11.8.1 Using the DMA

Since converted regular channel values are stored into a unique data register, it is useful to use DMA for conversion of more than one regular channel. This avoids the loss of the data already stored in the ADC\_DR register.

When the DMA mode is enabled (DMA bit set to 1 in the ADC\_CR2 register), after each conversion of a regular channel, a DMA request is generated. This allows the transfer of the converted data from the ADC\_DR register to the destination location selected by the software.

Despite this, if data are lost (overflow), the OVR bit in the ADC\_SR register is set and an interrupt is generated (if the OVRIE enable bit is set). DMA transfers are then disabled and DMA requests are no longer accepted. In this case, if a DMA request is made, the regular conversion in progress is aborted and further regular triggers are ignored. It is then necessary to clear the OVR flag and the DMAEN bit in the used DMA stream, and to re-initialize both the DMA and the ADC to have the wanted converted channel data transferred to the right memory location. Only then can the conversion be resumed and the data transfer, enabled again. Injected channel conversions are not impacted by overflow errors.

When OVR = 1 in DMA mode, the DMA requests are blocked after the last valid data have been transferred, which means that all the data transferred to the RAM can be considered as valid.

At the end of the last DMA transfer (number of transfers configured in the DMA controller's DMA\_SxNTR register):

- No new DMA request is issued to the DMA controller if the DDS bit is cleared to 0 in the ADC\_CR2 register (this avoids generating an overflow error). However the DMA bit is not cleared by hardware. It must be written to 0, then to 1 to start a new transfer.
- Requests can continue to be generated if the DDS bit is set to 1. This allows configuring the DMA in double-buffer circular mode.

To recover the ADC from OVR state when the DMA is used, follow the steps below:

1. Reinitialize the DMA (adjust destination address and NDTR counter)
2. Clear the ADC OVR bit in ADC\_SR register
3. Trigger the ADC to start the conversion.

### 11.8.2 Managing a sequence of conversions without using the DMA

If the conversions are slow enough, the conversion sequence can be handled by the software. In this case the EOCS bit must be set in the ADC\_CR2 register for the EOC status bit to be set at the end of each conversion, and not only at the end of the sequence. When EOCS = 1, overflow detection is automatically enabled. Thus, each time a conversion is complete, EOC is set and the ADC\_DR register can be read. The overflow management is the same as when the DMA is used.

To recover the ADC from OVR state when the EOCS is set, follow the steps below:

1. Clear the ADC OVR bit in ADC\_SR register
2. Trigger the ADC to start the conversion.

### 11.8.3 Conversions without DMA and without overrun detection

It may be useful to let the ADC convert one or more channels without reading the data each time (if there is an analog watchdog for instance). For that, the DMA must be disabled (DMA = 0) and the EOC bit must be set at the end of a sequence only (EOCS = 0). In this configuration, overrun detection is disabled.

## 11.9 Temperature sensor

The temperature sensor can be used to measure the ambient temperature ( $T_A$ ) of the device.

Figure 38 shows the block diagram of the temperature sensor.

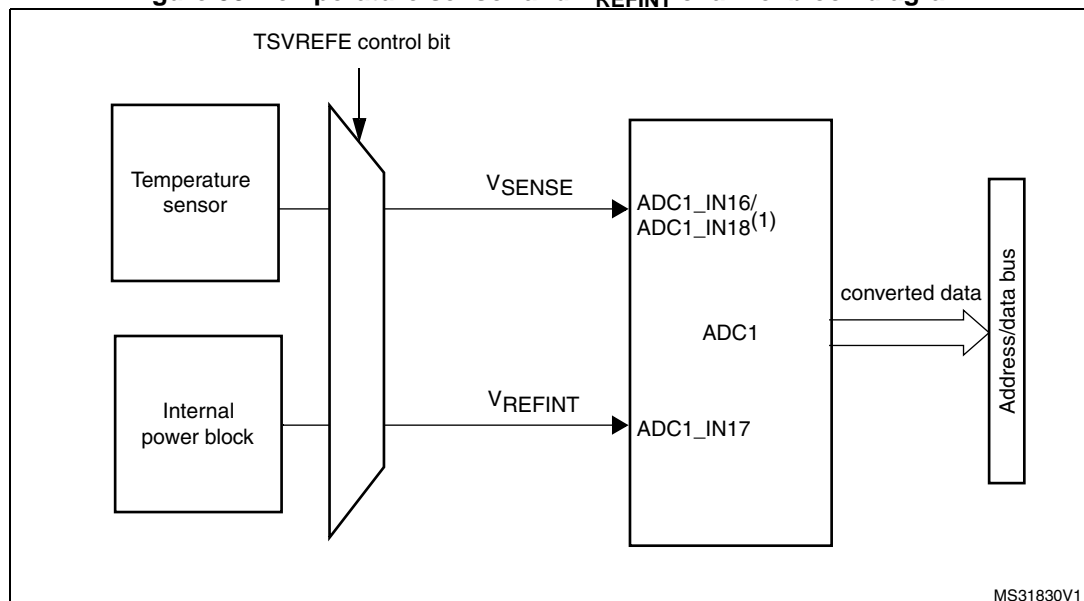
When not in use, the sensor can be put in power down mode.

*Note:* The TSVREFE bit must be set to enable the conversion of both internal channels: the ADC1\_IN16 or ADC1\_IN18 (temperature sensor) and the ADC1\_IN17 (VREFINT).

### Main features

- Supported temperature range:  $-40$  to  $125$  °C
- Precision:  $\pm 1.5$  °C

Figure 38. Temperature sensor and  $V_{REFINT}$  channel block diagram



1.  $V_{SENSE}$  is input to ADC1\_IN18

## Reading the temperature

To use the sensor:

3. Select ADC1\_IN16 or ADC1\_IN18 input channel.
4. Select a sampling time greater than the minimum sampling time specified in the datasheet.
5. Set the TSVREFE bit in the ADC\_CCR register to wake up the temperature sensor from power down mode
6. Start the ADC conversion by setting the SWSTART bit (or by external trigger)
7. Read the resulting  $V_{SENSE}$  data in the ADC data register
8. Calculate the temperature using the following formula:

$$\text{Temperature (in } ^\circ\text{C)} = \{(V_{SENSE} - V_{25}) / \text{Avg\_Slope}\} + 25$$

Where:

- $V_{25} = V_{SENSE}$  value for  $25^\circ\text{C}$
- Avg\_Slope = average slope of the temperature vs.  $V_{SENSE}$  curve (given in  $\text{mV}/^\circ\text{C}$  or  $\mu\text{V}/^\circ\text{C}$ )

Refer to the datasheet's electrical characteristics section for the actual values of  $V_{25}$  and Avg\_Slope.

*Note:* The sensor has a startup time after waking from power down mode before it can output  $V_{SENSE}$  at the correct level. The ADC also has a startup time after power-on, so to minimize the delay, the ADON and TSVREFE bits should be set at the same time.

The temperature sensor output voltage changes linearly with temperature. The offset of this linear function depends on each chip due to process variation (up to  $45^\circ\text{C}$  from one chip to another).

The internal temperature sensor is more suited for applications that detect temperature variations instead of absolute temperatures. If accurate temperature reading is required, an external temperature sensor should be used.

## 11.10 Battery charge monitoring

The VBATE bit in the ADC\_CCR register is used to switch to the battery voltage. As the  $V_{BAT}$  voltage could be higher than  $V_{DDA}$ , to ensure the correct operation of the ADC, the  $V_{BAT}$  pin is internally connected to a bridge divider.

When the VBATE is set, the bridge is automatically enabled to connect:

- $V_{BAT}/4$  to the ADC1\_IN18 input channel

*Note:* The VBAT and temperature sensor are connected to the same ADC internal channel (ADC1\_IN18). Only one conversion, either temperature sensor or VBAT, must be selected at a time. When both conversion are enabled simultaneously, only the VBAT conversion is performed.

## 11.11 ADC interrupts

An interrupt can be produced on the end of conversion for regular and injected groups, when the analog watchdog status bit is set and when the overrun status bit is set. Separate interrupt enable bits are available for flexibility.

Two other flags are present in the ADC\_SR register, but there is no interrupt associated with them:

- JSTRT (Start of conversion for channels of an injected group)
- STRT (Start of conversion for channels of a regular group)

**Table 45. ADC interrupts**

Interrupt event	Event flag	Enable control bit
End of conversion of a regular group	EOC	EOCIE
End of conversion of an injected group	JEOC	JEOCIE
Analog watchdog status bit is set	AWD	AWDIE
Overrun	OVR	OVRIE



## 11.12 ADC registers

Refer to [Section 1.1 on page 34](#) for a list of abbreviations used in register descriptions.

The peripheral registers must be written at word level (32 bits). Read accesses can be done by bytes (8 bits), half-words (16 bits) or words (32 bits).

### 11.12.1 ADC status register (ADC\_SR)

Address offset: 0x00

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved															
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved										OVR	STRT	JSTRT	JEOC	EOC	AWD
										rc_w0	rc_w0	rc_w0	rc_w0	rc_w0	rc_w0

Bits 31:6 Reserved, must be kept at reset value.

**Bit 5 OVR:** Overrun

This bit is set by hardware when data are lost . It is cleared by software. Overrun detection is enabled only when DMA = 1 or EOCS = 1.

- 0: No overrun occurred
- 1: Overrun has occurred

**Bit 4 STRT:** Regular channel start flag

This bit is set by hardware when regular channel conversion starts. It is cleared by software.

- 0: No regular channel conversion started
- 1: Regular channel conversion has started

**Bit 3 JSTRT:** Injected channel start flag

This bit is set by hardware when injected group conversion starts. It is cleared by software.

- 0: No injected group conversion started
- 1: Injected group conversion has started

**Bit 2 JEOC:** Injected channel end of conversion

This bit is set by hardware at the end of the conversion of all injected channels in the group. It is cleared by software.

- 0: Conversion is not complete
- 1: Conversion complete

**Bit 1 EOC:** Regular channel end of conversion

This bit is set by hardware at the end of the conversion of a regular group of channels. It is cleared by software or by reading the ADC\_DR register.

- 0: Conversion not complete (EOCS=0), or sequence of conversions not complete (EOCS=1)
- 1: Conversion complete (EOCS=0), or sequence of conversions complete (EOCS=1)

**Bit 0 AWD:** Analog watchdog flag

This bit is set by hardware when the converted voltage crosses the values programmed in the ADC\_LTR and ADC\_HTR registers. It is cleared by software.

- 0: No analog watchdog event occurred
- 1: Analog watchdog event occurred

### 11.12.2 ADC control register 1 (ADC\_CR1)

Address offset: 0x04

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved					OVRIE	RES		AWDEN	JAWDEN	Reserved					
					rw	rw	rw	rw	rw						
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
DISCNUM[2:0]			JDISCEN	DISCEN	JAUTO	AWDSGL	SCAN	JEOCIE	AWDIE	EOCIE	AWDCH[4:0]				
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 31:27 Reserved, must be kept at reset value.

Bit 26 **OVRIE**: Overrun interrupt enable

This bit is set and cleared by software to enable/disable the Overrun interrupt.

0: Overrun interrupt disabled

1: Overrun interrupt enabled. An interrupt is generated when the OVR bit is set.

Bits 25:24 **RES[1:0]**: Resolution

These bits are written by software to select the resolution of the conversion.

00: 12-bit (15 ADCCLK cycles)

01: 10-bit (13 ADCCLK cycles)

10: 8-bit (11 ADCCLK cycles)

11: 6-bit (9 ADCCLK cycles)

Bit 23 **AWDEN**: Analog watchdog enable on regular channels

This bit is set and cleared by software.

0: Analog watchdog disabled on regular channels

1: Analog watchdog enabled on regular channels

Bit 22 **JAWDEN**: Analog watchdog enable on injected channels

This bit is set and cleared by software.

0: Analog watchdog disabled on injected channels

1: Analog watchdog enabled on injected channels

Bits 21:16 Reserved, must be kept at reset value.

Bits 15:13 **DISCNUM[2:0]**: Discontinuous mode channel count

These bits are written by software to define the number of regular channels to be converted in discontinuous mode, after receiving an external trigger.

000: 1 channel

001: 2 channels

...

111: 8 channels

Bit 12 **JDISCEN**: Discontinuous mode on injected channels

This bit is set and cleared by software to enable/disable discontinuous mode on the injected channels of a group.

0: Discontinuous mode on injected channels disabled

1: Discontinuous mode on injected channels enabled

- Bit 11 **DISCEN**: Discontinuous mode on regular channels  
This bit is set and cleared by software to enable/disable Discontinuous mode on regular channels.  
0: Discontinuous mode on regular channels disabled  
1: Discontinuous mode on regular channels enabled
- Bit 10 **JAUTO**: Automatic injected group conversion  
This bit is set and cleared by software to enable/disable automatic injected group conversion after regular group conversion.  
0: Automatic injected group conversion disabled  
1: Automatic injected group conversion enabled
- Bit 9 **AWDSGL**: Enable the watchdog on a single channel in scan mode  
This bit is set and cleared by software to enable/disable the analog watchdog on the channel identified by the AWDCH[4:0] bits.  
0: Analog watchdog enabled on all channels  
1: Analog watchdog enabled on a single channel
- Bit 8 **SCAN**: Scan mode  
This bit is set and cleared by software to enable/disable the Scan mode. In Scan mode, the inputs selected through the ADC\_SQRx or ADC\_JSQRx registers are converted.  
0: Scan mode disabled  
1: Scan mode enabled  
*Note: An EOC interrupt is generated if the EOCIE bit is set:*
  - At the end of each regular group sequence if the EOCS bit is cleared to 0
  - At the end of each regular channel conversion if the EOCS bit is set to 1*Note: A JEOC interrupt is generated only on the end of conversion of the last channel if the JEOCIE bit is set.*
- Bit 7 **JEOCIE**: Interrupt enable for injected channels  
This bit is set and cleared by software to enable/disable the end of conversion interrupt for injected channels.  
0: JEOC interrupt disabled  
1: JEOC interrupt enabled. An interrupt is generated when the JEOC bit is set.
- Bit 6 **AWDIE**: Analog watchdog interrupt enable  
This bit is set and cleared by software to enable/disable the analog watchdog interrupt.  
0: Analog watchdog interrupt disabled  
1: Analog watchdog interrupt enabled
- Bit 5 **EOCIE**: Interrupt enable for EOC  
This bit is set and cleared by software to enable/disable the end of conversion interrupt.  
0: EOC interrupt disabled  
1: EOC interrupt enabled. An interrupt is generated when the EOC bit is set.
- Bits 4:0 **AWDCH[4:0]**: Analog watchdog channel select bits  
These bits are set and cleared by software. They select the input channel to be guarded by the analog watchdog.  
*Note:* 00000: ADC analog input Channel0  
00001: ADC analog input Channel1  
...  
01111: ADC analog input Channel15  
10000: ADC analog input Channel16  
10001: ADC analog input Channel17  
10010: ADC analog input Channel18  
Other values reserved

### 11.12.3 ADC control register 2 (ADC\_CR2)

Address offset: 0x08

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16		
reserved	SWST ART	EXTEN			EXTSEL[3:0]				reserved	JSWST ART	JEXTEN			JEXTSEL[3:0]			
	rw	rw	rw	rw	rw	rw	rw	rw		rw	rw	rw	rw	rw	rw	rw	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0		
reserved				ALIGN	EOCS	DDS	DMA	Reserved						CONT	ADON		
				rw	rw	rw	rw							rw	rw		

Bit 31 Reserved, must be kept at reset value.

Bit 30 **SWSTART**: Start conversion of regular channels

This bit is set by software to start conversion and cleared by hardware as soon as the conversion starts.

0: Reset state

1: Starts conversion of regular channels

*Note: This bit can be set only when ADON = 1 otherwise no conversion is launched.*

Bits 29:28 **EXTEN**: External trigger enable for regular channels

These bits are set and cleared by software to select the external trigger polarity and enable the trigger of a regular group.

00: Trigger detection disabled

01: Trigger detection on the rising edge

10: Trigger detection on the falling edge

11: Trigger detection on both the rising and falling edges

Bits 27:24 **EXTSEL[3:0]**: External event select for regular group

These bits select the external event used to trigger the start of conversion of a regular group:

0000: Timer 1 CC1 event

0001: Timer 1 CC2 event

0010: Timer 1 CC3 event

0011: Timer 2 CC2 event

0100: Timer 2 CC3 event

0101: Timer 2 CC4 event

0110: Timer 2 TRGO event

0111: Timer 3 CC1 event

1000: Timer 3 TRGO event

1001: Timer 4 CC4 event

1010: Timer 5 CC1 event

1011: Timer 5 CC2 event

1100: Timer 5 CC3 event

1101: Reserved

1110: Reserved

1111: EXTI line11

Bit 23 Reserved, must be kept at reset value.

- Bit 22 **JSWSTART**: Start conversion of injected channels  
This bit is set by software and cleared by hardware as soon as the conversion starts.  
0: Reset state  
1: Starts conversion of injected channels  
*Note: This bit can be set only when ADON = 1 otherwise no conversion is launched.*
- Bits 21:20 **JEXTEN**: External trigger enable for injected channels  
These bits are set and cleared by software to select the external trigger polarity and enable the trigger of an injected group.  
00: Trigger detection disabled  
01: Trigger detection on the rising edge  
10: Trigger detection on the falling edge  
11: Trigger detection on both the rising and falling edges
- Bits 19:16 **JEXTSEL[3:0]**: External event select for injected group  
These bits select the external event used to trigger the start of conversion of an injected group.  
0000: Timer 1 CC4 event  
0001: Timer 1 TRGO event  
0010: Timer 2 CC1 event  
0011: Timer 2 TRGO event  
0100: Timer 3 CC2 event  
0101: Timer 3 CC4 event  
0110: Timer 4 CC1 event  
0111: Timer 4 CC2 event  
1000: Timer 4 CC3 event  
1001: Timer 4 TRGO event  
1010: Timer 5 CC4 event  
1011: Timer 5 TRGO event  
1100: Reserved  
1101: Reserved  
1110: Reserved  
1111: EXTI line15
- Bits 15:12 Reserved, must be kept at reset value.
- Bit 11 **ALIGN**: Data alignment  
This bit is set and cleared by software. Refer to [Figure 35](#) and [Figure 36](#).  
0: Right alignment  
1: Left alignment
- Bit 10 **EOCS**: End of conversion selection  
This bit is set and cleared by software.  
0: The EOC bit is set at the end of each sequence of regular conversions. Overrun detection is enabled only if DMA=1.  
1: The EOC bit is set at the end of each regular conversion. Overrun detection is enabled.
- Bit 9 **DDS**: DMA disable selection (for single ADC mode)  
This bit is set and cleared by software.  
0: No new DMA request is issued after the last transfer (as configured in the DMA controller)  
1: DMA requests are issued as long as data are converted and DMA=1
- Bit 8 **DMA**: Direct memory access mode (for single ADC mode)  
This bit is set and cleared by software. Refer to the DMA controller chapter for more details.  
0: DMA mode disabled  
1: DMA mode enabled

Bits 7:2 Reserved, must be kept at reset value.

Bit 1 **CONT**: Continuous conversion

This bit is set and cleared by software. If it is set, conversion takes place continuously until it is cleared.

- 0: Single conversion mode
- 1: Continuous conversion mode

Bit 0 **ADON**: A/D Converter ON / OFF

This bit is set and cleared by software.

- Note:
- 0: Disable ADC conversion and go to power down mode
  - 1: Enable ADC

### 11.12.4 ADC sample time register 1 (ADC\_SMPR1)

Address offset: 0x0C

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved					SMP18[2:0]			SMP17[2:0]			SMP16[2:0]			SMP15[2:1]	
					rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
SMP15_0	SMP14[2:0]			SMP13[2:0]			SMP12[2:0]			SMP11[2:0]			SMP10[2:0]		
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	

Bits 31: 27 Reserved, must be kept at reset value.

Bits 26:0 **SMPx[2:0]**: Channel x sampling time selection

These bits are written by software to select the sampling time individually for each channel. During sampling cycles, the channel selection bits must remain unchanged.

- Note:
- 000: 3 cycles
  - 001: 15 cycles
  - 010: 28 cycles
  - 011: 56 cycles
  - 100: 84 cycles
  - 101: 112 cycles
  - 110: 144 cycles
  - 111: 480 cycles

### 11.12.5 ADC sample time register 2 (ADC\_SMPR2)

Address offset: 0x10

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	
Reserved			SMP9[2:0]			SMP8[2:0]			SMP7[2:0]			SMP6[2:0]			SMP5[2:1]	
			rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
SMP5_0	SMP4[2:0]			SMP3[2:0]			SMP2[2:0]			SMP1[2:0]			SMP0[2:0]			
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw		



Bits 31:30 Reserved, must be kept at reset value.

Bits 29:0 **SMPx[2:0]**: Channel x sampling time selection

These bits are written by software to select the sampling time individually for each channel. During sample cycles, the channel selection bits must remain unchanged.

- Note:
- 000: 3 cycles
  - 001: 15 cycles
  - 010: 28 cycles
  - 011: 56 cycles
  - 100: 84 cycles
  - 101: 112 cycles
  - 110: 144 cycles
  - 111: 480 cycles

### 11.12.6 ADC injected channel data offset register x (ADC\_JOFRx) (x=1..4)

Address offset: 0x14-0x20

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved															
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved				JOFFSETx[11:0]											
				rw											

Bits 31:12 Reserved, must be kept at reset value.

Bits 11:0 **JOFFSETx[11:0]**: Data offset for injected channel x

These bits are written by software to define the offset to be subtracted from the raw converted data when converting injected channels. The conversion result can be read from in the ADC\_JDRx registers.

### 11.12.7 ADC watchdog higher threshold register (ADC\_HTR)

Address offset: 0x24

Reset value: 0x0000 0FFF

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved															
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved				HT[11:0]											
				rw											

Bits 31:12 Reserved, must be kept at reset value.

Bits 11:0 **HT[11:0]**: Analog watchdog higher threshold

These bits are written by software to define the higher threshold for the analog watchdog.

### 11.12.8 ADC watchdog lower threshold register (ADC\_LTR)

Address offset: 0x28

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved															
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved				LT[11:0]											
				rw											

Bits 31:12 Reserved, must be kept at reset value.

Bits 11:0 **LT[11:0]**: Analog watchdog lower threshold

These bits are written by software to define the lower threshold for the analog watchdog.

### 11.12.9 ADC regular sequence register 1 (ADC\_SQR1)

Address offset: 0x2C

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved								L[3:0]				SQ16[4:1]			
								rw				rw			
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
SQ16_0		SQ15[4:0]				SQ14[4:0]				SQ13[4:0]					
rw		rw				rw				rw					

Bits 31:24 Reserved, must be kept at reset value.

Bits 23:20 **L[3:0]**: Regular channel sequence length

These bits are written by software to define the total number of conversions in the regular channel conversion sequence.

0000: 1 conversion

0001: 2 conversions

...

1111: 16 conversions

Bits 19:15 **SQ16[4:0]**: 16th conversion in regular sequence

These bits are written by software with the channel number (0..18) assigned as the 16th in the conversion sequence.

Bits 14:10 **SQ15[4:0]**: 15th conversion in regular sequence

Bits 9:5 **SQ14[4:0]**: 14th conversion in regular sequence

Bits 4:0 **SQ13[4:0]**: 13th conversion in regular sequence



### 11.12.10 ADC regular sequence register 2 (ADC\_SQR2)

Address offset: 0x30

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved		SQ12[4:0]					SQ11[4:0]					SQ10[4:1]			
		rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
SQ10_0		SQ9[4:0]					SQ8[4:0]					SQ7[4:0]			
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 31:30 Reserved, must be kept at reset value.

Bits 29:26 **SQ12[4:0]**: 12th conversion in regular sequence

These bits are written by software with the channel number (0..18) assigned as the 12th in the sequence to be converted.

Bits 24:20 **SQ11[4:0]**: 11th conversion in regular sequence

Bits 19:15 **SQ10[4:0]**: 10th conversion in regular sequence

Bits 14:10 **SQ9[4:0]**: 9th conversion in regular sequence

Bits 9:5 **SQ8[4:0]**: 8th conversion in regular sequence

Bits 4:0 **SQ7[4:0]**: 7th conversion in regular sequence

### 11.12.11 ADC regular sequence register 3 (ADC\_SQR3)

Address offset: 0x34

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved		SQ6[4:0]					SQ5[4:0]					SQ4[4:1]			
		rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
SQ4_0		SQ3[4:0]					SQ2[4:0]					SQ1[4:0]			
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 31:30 Reserved, must be kept at reset value.

Bits 29:25 **SQ6[4:0]**: 6th conversion in regular sequence

These bits are written by software with the channel number (0..18) assigned as the 6th in the sequence to be converted.

Bits 24:20 **SQ5[4:0]**: 5th conversion in regular sequence

Bits 19:15 **SQ4[4:0]**: 4th conversion in regular sequence

Bits 14:10 **SQ3[4:0]**: 3rd conversion in regular sequence

Bits 9:5 **SQ2[4:0]**: 2nd conversion in regular sequence

Bits 4:0 **SQ1[4:0]**: 1st conversion in regular sequence

### 11.12.12 ADC injected sequence register (ADC\_JSQR)

Address offset: 0x38

Reset value: 0x0000 0000

	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved											JL[1:0]		JSQ4[4:1]			
											rw	rw	rw	rw	rw	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
JSQ4[0]		JSQ3[4:0]				JSQ2[4:0]				JSQ1[4:0]						
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 31:22 Reserved, must be kept at reset value.

Bits 21:20 **JL[1:0]**: Injected sequence length

These bits are written by software to define the total number of conversions in the injected channel conversion sequence.

- 00: 1 conversion
- 01: 2 conversions
- 10: 3 conversions
- 11: 4 conversions

Bits 19:15 **JSQ4[4:0]**: 4th conversion in injected sequence (when JL[1:0]=3, see note below)

These bits are written by software with the channel number (0..18) assigned as the 4th in the sequence to be converted.

Bits 14:10 **JSQ3[4:0]**: 3rd conversion in injected sequence (when JL[1:0]=3, see note below)

Bits 9:5 **JSQ2[4:0]**: 2nd conversion in injected sequence (when JL[1:0]=3, see note below)

Bits 4:0 **JSQ1[4:0]**: 1st conversion in injected sequence (when JL[1:0]=3, see note below)

*Note:* When JL[1:0]=3 (4 injected conversions in the sequencer), the ADC converts the channels in the following order: JSQ1[4:0], JSQ2[4:0], JSQ3[4:0], and JSQ4[4:0].

When JL=2 (3 injected conversions in the sequencer), the ADC converts the channels in the following order: JSQ2[4:0], JSQ3[4:0], and JSQ4[4:0].

When JL=1 (2 injected conversions in the sequencer), the ADC converts the channels in starting from JSQ3[4:0], and then JSQ4[4:0].

When JL=0 (1 injected conversion in the sequencer), the ADC converts only JSQ4[4:0] channel.

### 11.12.13 ADC injected data register x (ADC\_JDRx) (x= 1..4)

Address offset: 0x3C - 0x48

Reset value: 0x0000 0000

	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved																
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
JDATA[15:0]																
r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r



Bits 31:16 Reserved, must be kept at reset value.

Bits 15:0 **JDATA[15:0]**: Injected data

These bits are read-only. They contain the conversion result from injected channel x. The data are left -or right-aligned as shown in [Figure 35](#) and [Figure 36](#).

### 11.12.14 ADC regular data register (ADC\_DR)

Address offset: 0x4C

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved															
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
DATA[15:0]															
r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r

Bits 31:16 Reserved, must be kept at reset value.

Bits 15:0 **DATA[15:0]**: Regular data

These bits are read-only. They contain the conversion result from the regular channels. The data are left- or right-aligned as shown in [Figure 35](#) and [Figure 36](#).

### 11.12.15 ADC common control register (ADC\_CCR)

Address offset: 0x04 (this offset address is relative to ADC1 base address + 0x300)

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved								TSVREFE	VBATE	Reserved				ADCPRE	
								rw	rw					rw	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved															

Bits 31:24 Reserved, must be kept at reset value.

Bit 23 **TSVREFE**: Temperature sensor and V<sub>REFINT</sub> enable

This bit is set and cleared by software to enable/disable the temperature sensor and the V<sub>REFINT</sub> channel.

0: Temperature sensor and V<sub>REFINT</sub> channel disabled

1: Temperature sensor and V<sub>REFINT</sub> channel enabled

*Note: VBATE must be disabled when TSVREFE is set. If both bits are set, only the VBAT conversion is performed.*

Bit 22 **VBATE**: V<sub>BAT</sub> enable

This bit is set and cleared by software to enable/disable the V<sub>BAT</sub> channel.

0: V<sub>BAT</sub> channel disabled

1: V<sub>BAT</sub> channel enabled

Bits 21:18 Reserved, must be kept at reset value.

Bits 17:16 **ADCPRE**: ADC prescaler

Set and cleared by software to select the frequency of the clock to the ADC. .

- Note: 00: PCLK2 divided by 2
- 01: PCLK2 divided by 4
- 10: PCLK2 divided by 6
- 11: PCLK2 divided by 8

Bits 15:0 Reserved, must be kept at reset value.

### 11.12.16 ADC register map

The following table summarizes the ADC registers.

**Table 46. ADC global register map**

Offset	Register
0x000 - 0x04C	ADC1
0x050 - 0x0FC	Reserved
0x100 - 0x14C	Reserved
0x118 - 0x1FC	Reserved
0x200 - 0x24C	Reserved
0x250 - 0x2FC	Reserved
0x300 - 0x308	Common registers

**Table 47. ADC register map and reset values for each ADC**

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0		
0x00	<b>ADC_SR</b>	Reserved																								OVR	STRT	JSTRT	JEOC	EOC	AWD				
	Reset value																									0	0	0	0	0	0				
0x04	<b>ADC_CR1</b>	Reserved				OVRIE	RES[1:0]	AWDEN	JAWDEN	Reserved				DISC NUM [2:0]		JDISEN	DISCEN	JAUTO	AWD SGL	SCAN	JEOCIE	AWDIE	EOCIE	AWDCH[4:0]											
	Reset value					0	0	0	0					0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0		
0x08	<b>ADC_CR2</b>	Reset	SWSTART	EXTEN[1:0]	EXTSEL [3:0]			Reset	JSWSTART	JEXTEN[1:0]	JEXTSEL [3:0]			Reserved				ALIGN	EOCS	DDS	DMA	Reserved				CONT	ADON								
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0			
0x0C	<b>ADC_SMPR1</b>	Sample time bits SMPx_x																																	
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0		
0x10	<b>ADC_SMPR2</b>	Sample time bits SMPx_x																																	
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0		
0x14	<b>ADC_JOFR1</b>	Reserved																		JOFFSET1[11:0]															
	Reset value																			0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x18	<b>ADC_JOFR2</b>	Reserved																		JOFFSET2[11:0]															
	Reset value																			0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0



**Table 47. ADC register map and reset values for each ADC (continued)**

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0x1C	ADC_JOFR3	Reserved											JOFFSET3[11:0]																				
	Reset value	0											0																				
0x20	ADC_JOFR4	Reserved											JOFFSET4[11:0]																				
	Reset value	0											0																				
0x24	ADC_HTR	Reserved											HT[11:0]																				
	Reset value	1											1																				
0x28	ADC_LTR	Reserved											LT[11:0]																				
	Reset value	0											0																				
0x2C	ADC_SQR1	Reserved						L[3:0]			Regular channel sequence SQx_x bits																						
	Reset value	0						0			0																						
0x30	ADC_SQR2	Reserved	Regular channel sequence SQx_x bits																														
	Reset value		0																														
0x34	ADC_SQR3	Reserved	Regular channel sequence SQx_x bits																														
	Reset value		0																														
0x38	ADC_JSQR	Reserved						JL[1:0]			Injected channel sequence JSQx_x bits																						
	Reset value	0						0			0																						
0x3C	ADC_JDR1	Reserved											JDATA[15:0]																				
	Reset value	0											0																				
0x40	ADC_JDR2	Reserved											JDATA[15:0]																				
	Reset value	0											0																				
0x44	ADC_JDR3	Reserved											JDATA[15:0]																				
	Reset value	0											0																				
0x48	ADC_JDR4	Reserved											JDATA[15:0]																				
	Reset value	0											0																				
0x4C	ADC_DR	Reserved											Regular DATA[15:0]																				
	Reset value	0											0																				

**Table 48. ADC register map and reset values (common ADC registers)**

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0x04	ADC_CCR	Reserved						TSVREFE	VBATE	Reserved						ADCPRE[1:0]	Reserved																
	Reset value	0						0	0	0						0	0	0															

Refer to [Table 1 on page 38](#) for the register boundary addresses.

## 12 Advanced-control timer (TIM1)

TIM8 is not available in STM32F401xB/C and STM32F401xD/E.

### 12.1 TIM1 introduction

The advanced-control timers (TIM1) consist of a 16-bit auto-reload counter driven by a programmable prescaler.

It may be used for a variety of purposes, including measuring the pulse lengths of input signals (input capture) or generating output waveforms (output compare, PWM, complementary PWM with dead-time insertion).

Pulse lengths and waveform periods can be modulated from a few microseconds to several milliseconds using the timer prescaler and the RCC clock controller prescalers.

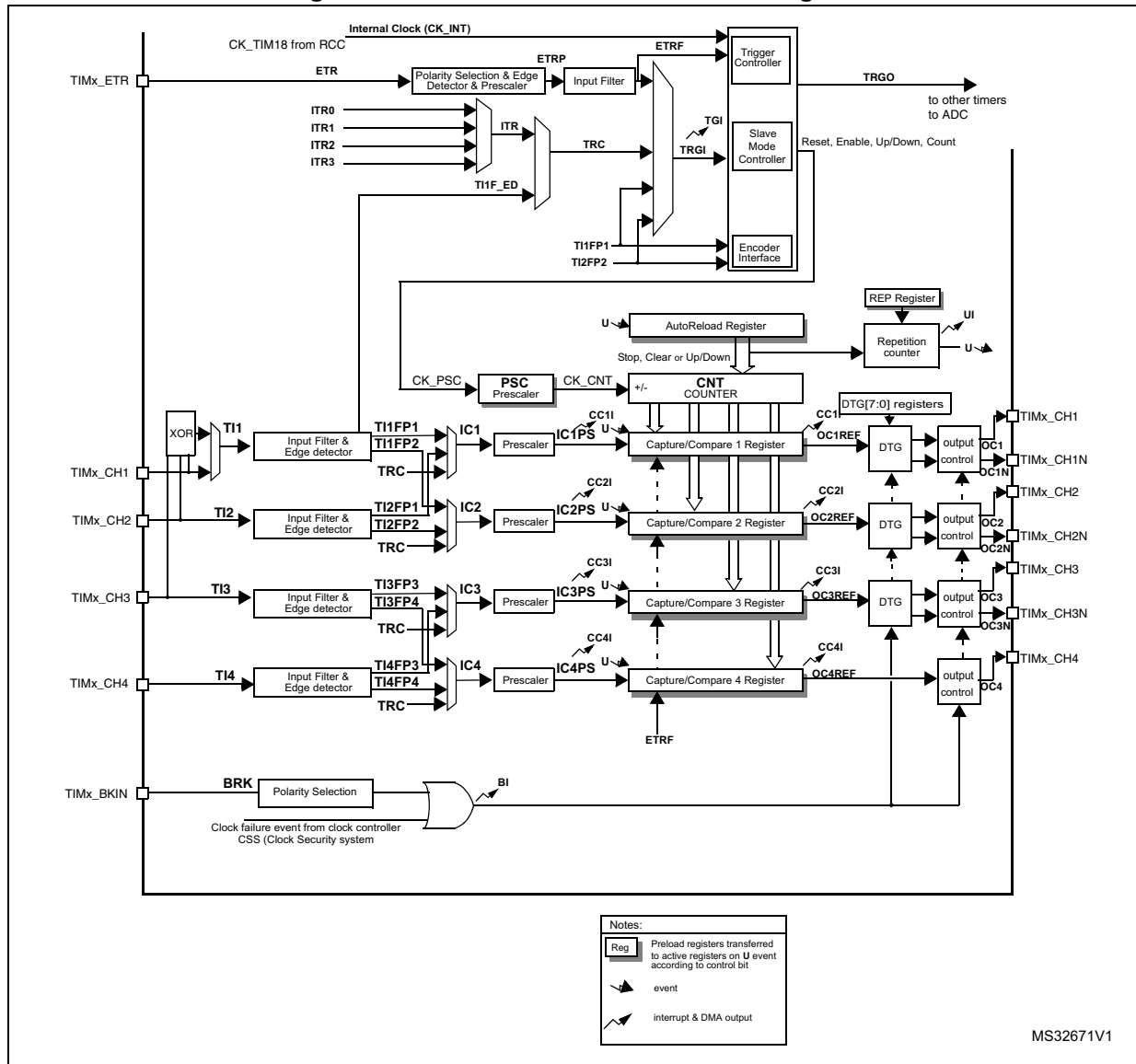
The advanced-control (TIM1) and general-purpose (TIMx) timers are completely independent, and do not share any resources. They can be synchronized together as described in [Section 12.3.20](#).

## 12.2 TIM1 main features

TIM1 timer features include:

- 16-bit up, down, up/down auto-reload counter.
- 16-bit programmable prescaler allowing dividing (also “on the fly”) the counter clock frequency either by any factor between 1 and 65536.
- Up to 4 independent channels for:
  - Input Capture
  - Output Compare
  - PWM generation (Edge and Center-aligned Mode)
  - One-pulse mode output
- Complementary outputs with programmable dead-time
- Synchronization circuit to control the timer with external signals and to interconnect several timers together.
- Repetition counter to update the timer registers only after a given number of cycles of the counter.
- Break input to put the timer’s output signals in reset state or in a known state.
- Interrupt/DMA generation on the following events:
  - Update: counter overflow/underflow, counter initialization (by software or internal/external trigger)
  - Trigger event (counter start, stop, initialization or count by internal/external trigger)
  - Input capture
  - Output compare
  - Break input
- Supports incremental (quadrature) encoder and hall-sensor circuitry for positioning purposes
- Trigger input for external clock or cycle-by-cycle current management

Figure 39. Advanced-control timer block diagram





## 12.3 TIM1 functional description

### 12.3.1 Time-base unit

The main block of the programmable advanced-control timer is a 16-bit counter with its related auto-reload register. The counter can count up, down or both up and down. The counter clock can be divided by a prescaler.

The counter, the auto-reload register and the prescaler register can be written or read by software. This is true even when the counter is running.

The time-base unit includes:

- Counter register (TIMx\_CNT)
- Prescaler register (TIMx\_PSC)
- Auto-reload register (TIMx\_ARR)
- Repetition counter register (TIMx\_RCR)

The auto-reload register is preloaded. Writing to or reading from the auto-reload register accesses the preload register. The content of the preload register are transferred into the shadow register permanently or at each update event (UEV), depending on the auto-reload preload enable bit (ARPE) in TIMx\_CR1 register. The update event is sent when the counter reaches the overflow (or underflow when downcounting) and if the UDIS bit equals 0 in the TIMx\_CR1 register. It can also be generated by software. The generation of the update event is described in detailed for each configuration.

The counter is clocked by the prescaler output CK\_CNT, which is enabled only when the counter enable bit (CEN) in TIMx\_CR1 register is set (refer also to the slave mode controller description to get more details on counter enabling).

Note that the counter starts counting 1 clock cycle after setting the CEN bit in the TIMx\_CR1 register.

#### Prescaler description

The prescaler can divide the counter clock frequency by any factor between 1 and 65536. It is based on a 16-bit counter controlled through a 16-bit register (in the TIMx\_PSC register). It can be changed on the fly as this control register is buffered. The new prescaler ratio is taken into account at the next update event.

*Figure 40* and *Figure 41* give some examples of the counter behavior when the prescaler ratio is changed on the fly:

Figure 40. Counter timing diagram with prescaler division change from 1 to 2

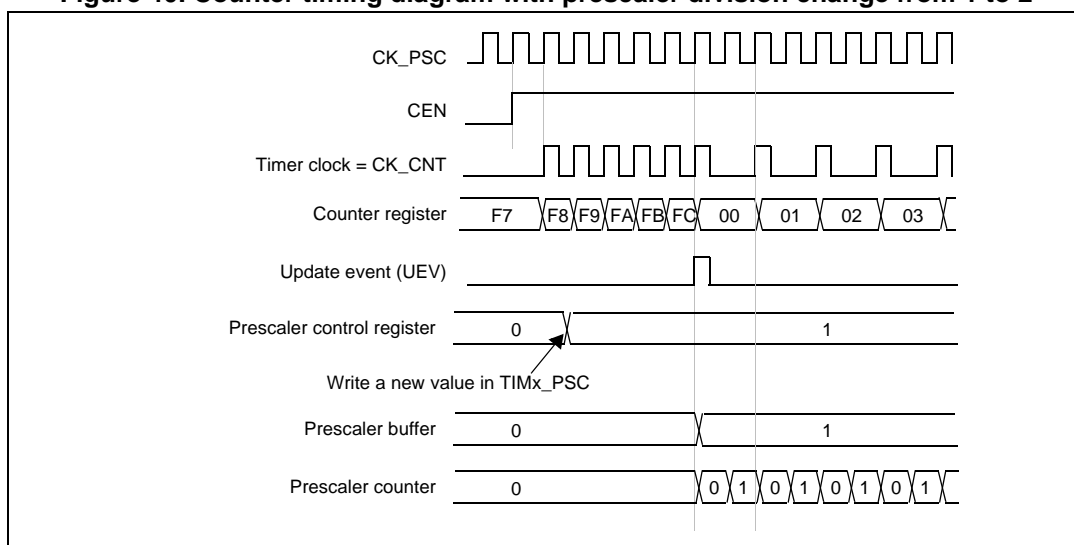
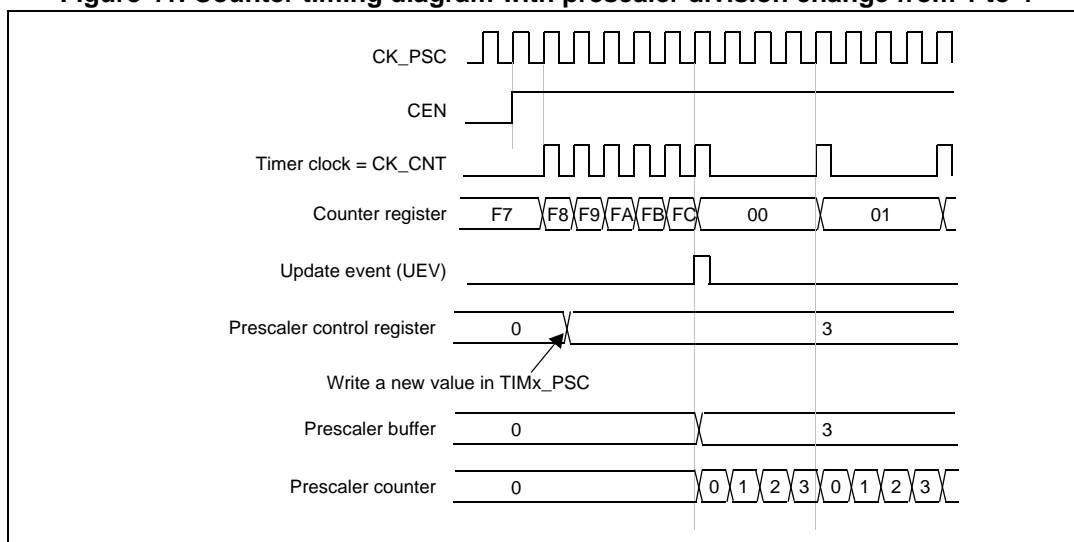


Figure 41. Counter timing diagram with prescaler division change from 1 to 4



### 12.3.2 Counter modes

#### Upcounting mode

In upcounting mode, the counter counts from 0 to the auto-reload value (content of the TIMx\_ARR register), then restarts from 0 and generates a counter overflow event.

If the repetition counter is used, the update event (UEV) is generated after upcounting is repeated for the number of times programmed in the repetition counter register (TIMx\_RCR). Else the update event is generated at each counter overflow.

Setting the UG bit in the TIMx\_EGR register (by software or by using the slave mode controller) also generates an update event.

The UEV event can be disabled by software by setting the UDIS bit in the TIMx\_CR1 register. This is to avoid updating the shadow registers while writing new values in the

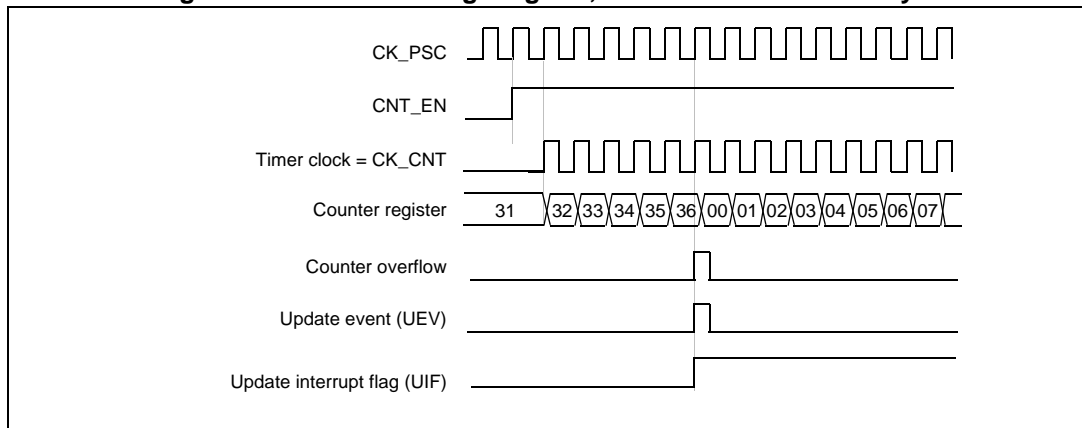
preload registers. Then no update event occurs until the UDIS bit has been written to 0. However, the counter restarts from 0, as well as the counter of the prescaler (but the prescale rate does not change). In addition, if the URS bit (update request selection) in TIMx\_CR1 register is set, setting the UG bit generates an update event UEV but without setting the UIF flag (thus no interrupt or DMA request is sent). This is to avoid generating both update and capture interrupts when clearing the counter on the capture event.

When an update event occurs, all the registers are updated and the update flag (UIF bit in TIMx\_SR register) is set (depending on the URS bit):

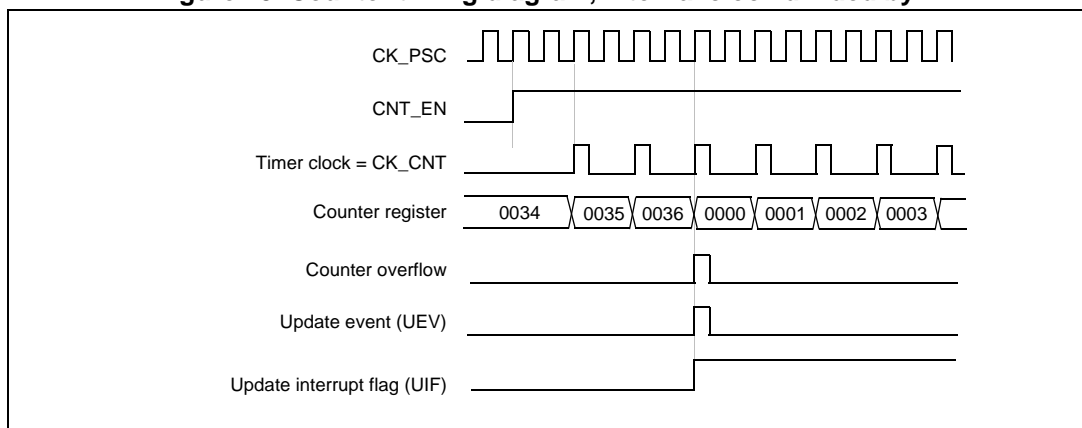
- The repetition counter is reloaded with the content of TIMx\_RCR register,
- The auto-reload shadow register is updated with the preload value (TIMx\_ARR),
- The buffer of the prescaler is reloaded with the preload value (content of the TIMx\_PSC register).

The following figures show some examples of the counter behavior for different clock frequencies when TIMx\_ARR=0x36.

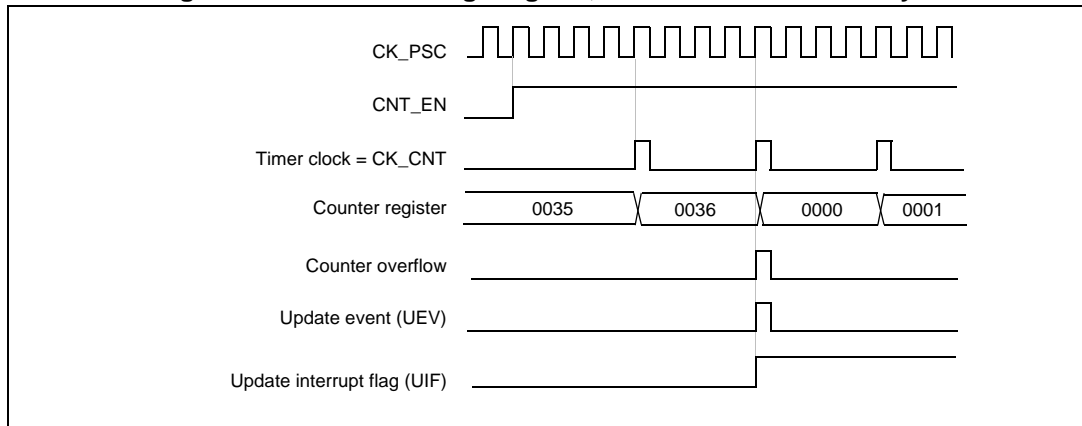
**Figure 42. Counter timing diagram, internal clock divided by 1**



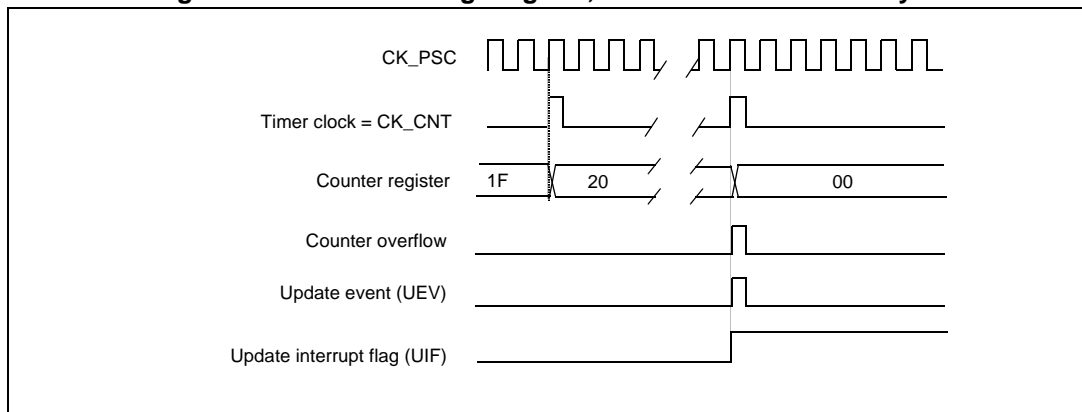
**Figure 43. Counter timing diagram, internal clock divided by 2**



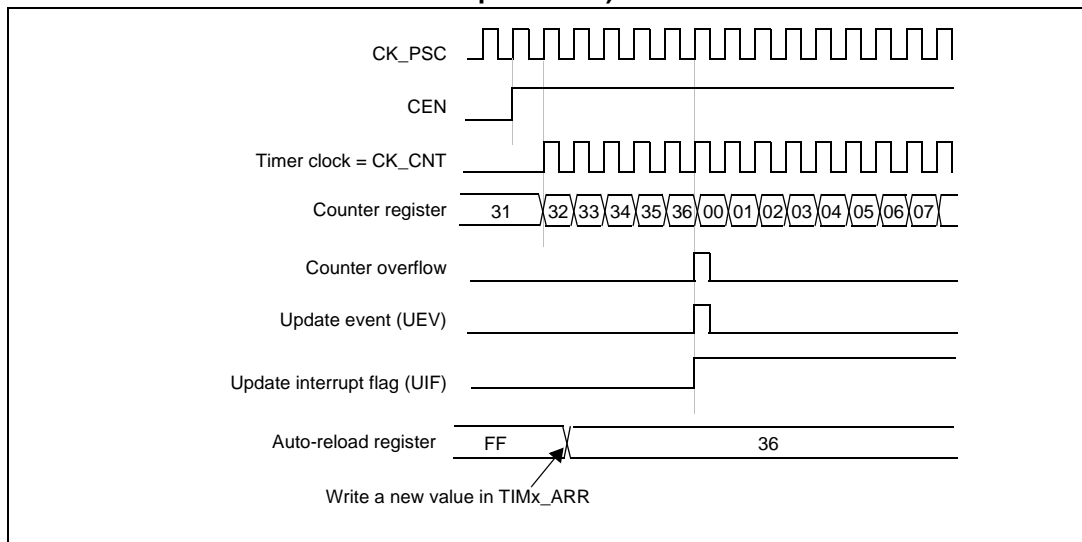
**Figure 44. Counter timing diagram, internal clock divided by 4**



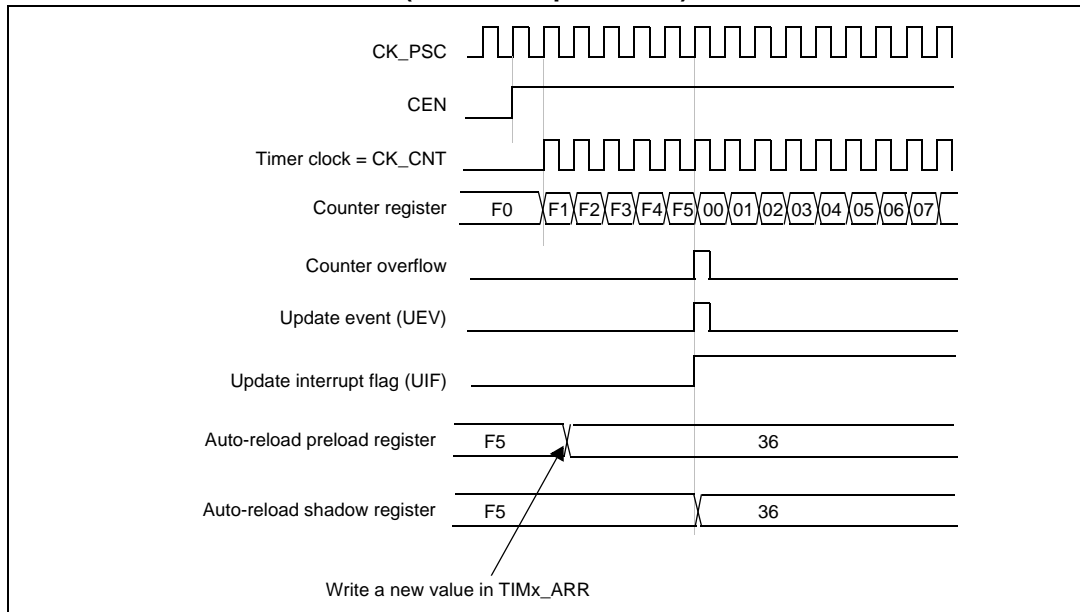
**Figure 45. Counter timing diagram, internal clock divided by N**



**Figure 46. Counter timing diagram, update event when ARPE=0 (TIMx\_ARR not preloaded)**



**Figure 47. Counter timing diagram, update event when ARPE=1 (TIMx\_ARR preloaded)**



### Downcounting mode

In downcounting mode, the counter counts from the auto-reload value (content of the TIMx\_ARR register) down to 0, then restarts from the auto-reload value and generates a counter underflow event.

If the repetition counter is used, the update event (UEV) is generated after downcounting is repeated for the number of times programmed in the repetition counter register plus one (TIMx\_RCR+1). Else the update event is generated at each counter underflow.

Setting the UG bit in the TIMx\_EGR register (by software or by using the slave mode controller) also generates an update event.

The UEV update event can be disabled by software by setting the UDIS bit in TIMx\_CR1 register. This is to avoid updating the shadow registers while writing new values in the preload registers. Then no update event occurs until UDIS bit has been written to 0. However, the counter restarts from the current auto-reload value, whereas the counter of the prescaler restarts from 0 (but the prescale rate doesn't change).

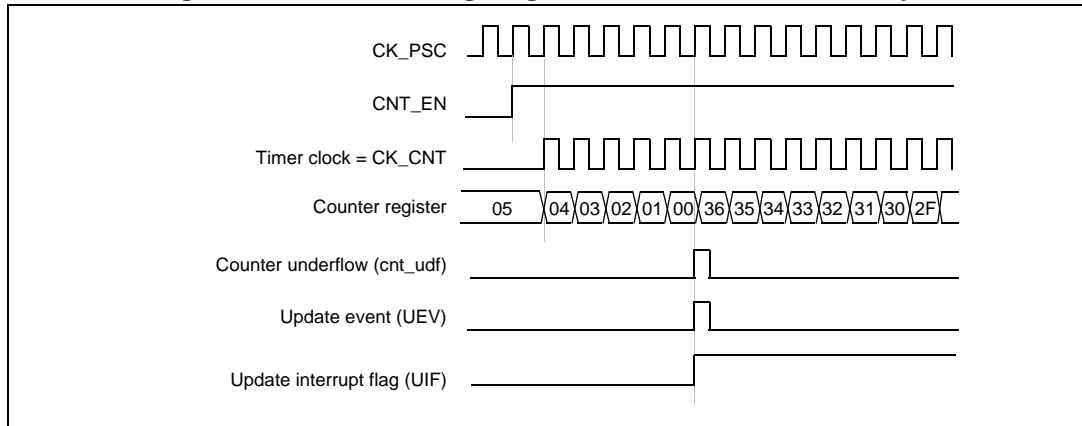
In addition, if the URS bit (update request selection) in TIMx\_CR1 register is set, setting the UG bit generates an update event UEV but without setting the UIF flag (thus no interrupt or DMA request is sent). This is to avoid generating both update and capture interrupts when clearing the counter on the capture event.

When an update event occurs, all the registers are updated and the update flag (UIF bit in TIMx\_SR register) is set (depending on the URS bit):

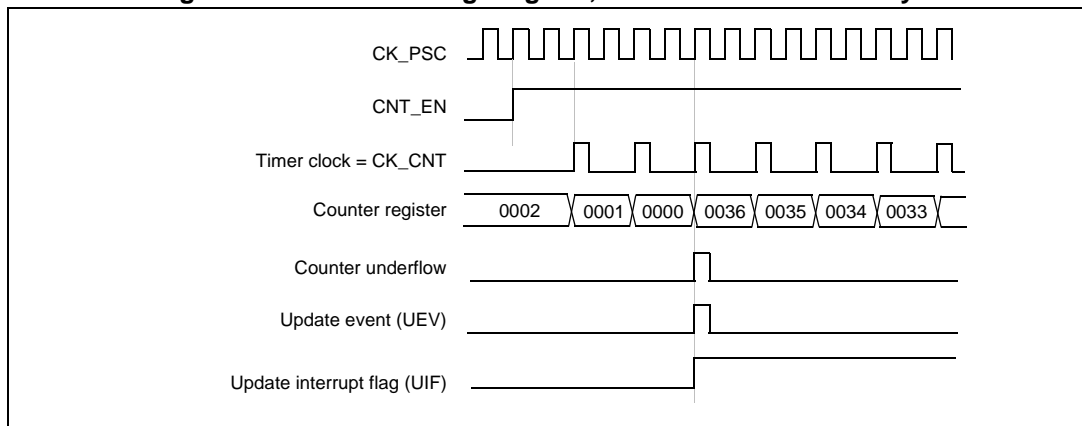
- The repetition counter is reloaded with the content of TIMx\_RCR register
- The buffer of the prescaler is reloaded with the preload value (content of the TIMx\_PSC register)
- The auto-reload active register is updated with the preload value (content of the TIMx\_ARR register). Note that the auto-reload is updated before the counter is reloaded, so that the next period is the expected one

The following figures show some examples of the counter behavior for different clock frequencies when TIMx\_ARR=0x36.

**Figure 48. Counter timing diagram, internal clock divided by 1**



**Figure 49. Counter timing diagram, internal clock divided by 2**



**Figure 50. Counter timing diagram, internal clock divided by 4**

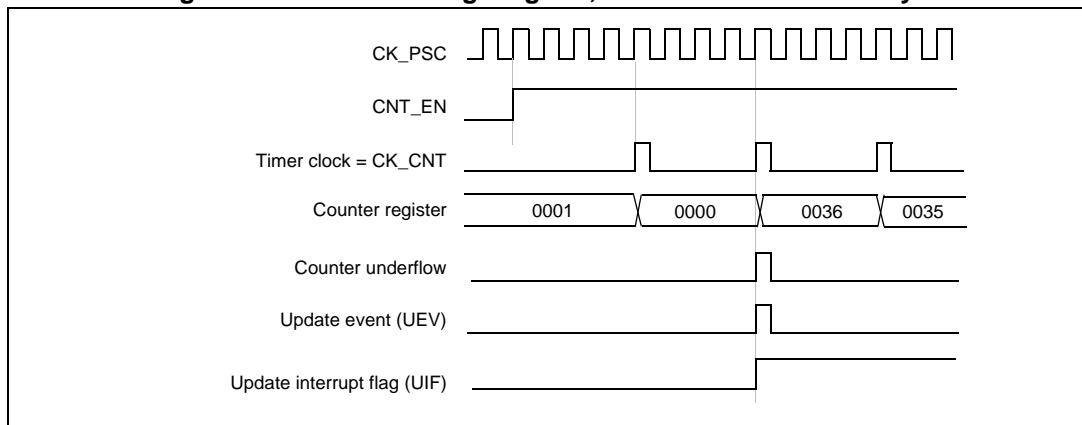


Figure 51. Counter timing diagram, internal clock divided by N

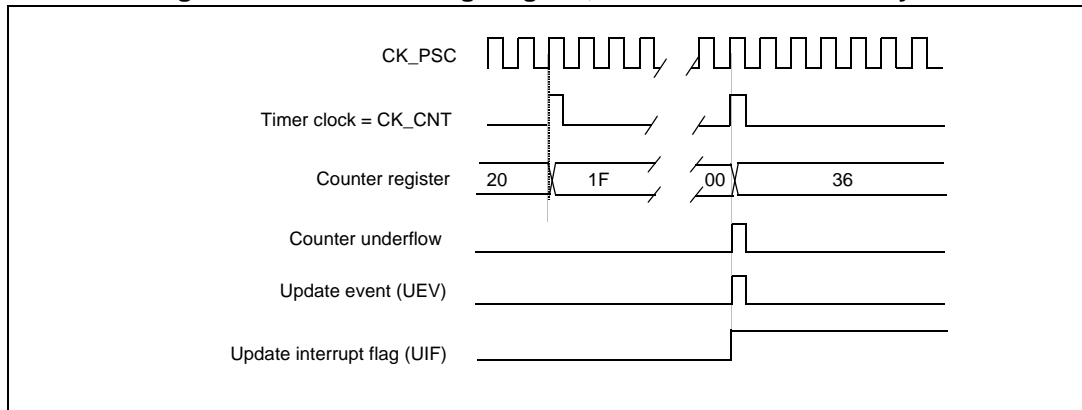
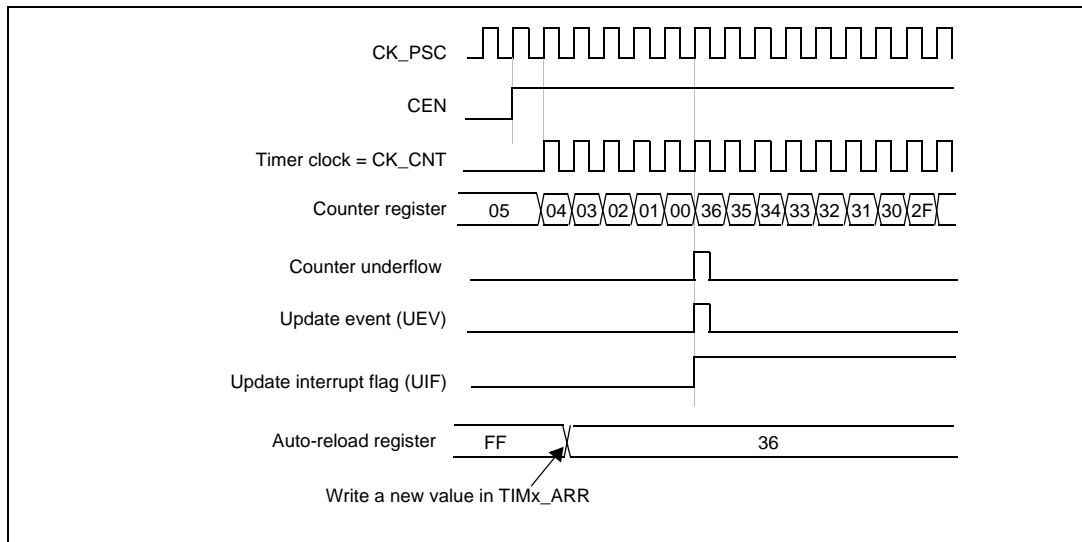


Figure 52. Counter timing diagram, update event when repetition counter is not used



**Center-aligned mode (up/down counting)**

In center-aligned mode, the counter counts from 0 to the auto-reload value (content of the TIMx\_ARR register) – 1, generates a counter overflow event, then counts from the auto-reload value down to 1 and generates a counter underflow event. Then it restarts counting from 0.

Center-aligned mode is active when the CMS bits in TIMx\_CR1 register are not equal to '00'. The Output compare interrupt flag of channels configured in output is set when: the counter counts down (Center aligned mode 1, CMS = "01"), the counter counts up (Center aligned mode 2, CMS = "10") the counter counts up and down (Center aligned mode 3, CMS = "11").

In this mode, the DIR direction bit in the TIMx\_CR1 register cannot be written. It is updated by hardware and gives the current direction of the counter.

The update event can be generated at each counter overflow and at each counter underflow or by setting the UG bit in the TIMx\_EGR register (by software or by using the slave mode controller) also generates an update event. In this case, the counter restarts counting from 0, as well as the counter of the prescaler.

The UEV update event can be disabled by software by setting the UDIS bit in the TIMx\_CR1 register. This is to avoid updating the shadow registers while writing new values in the preload registers. Then no update event occurs until UDIS bit has been written to 0. However, the counter continues counting up and down, based on the current auto-reload value.

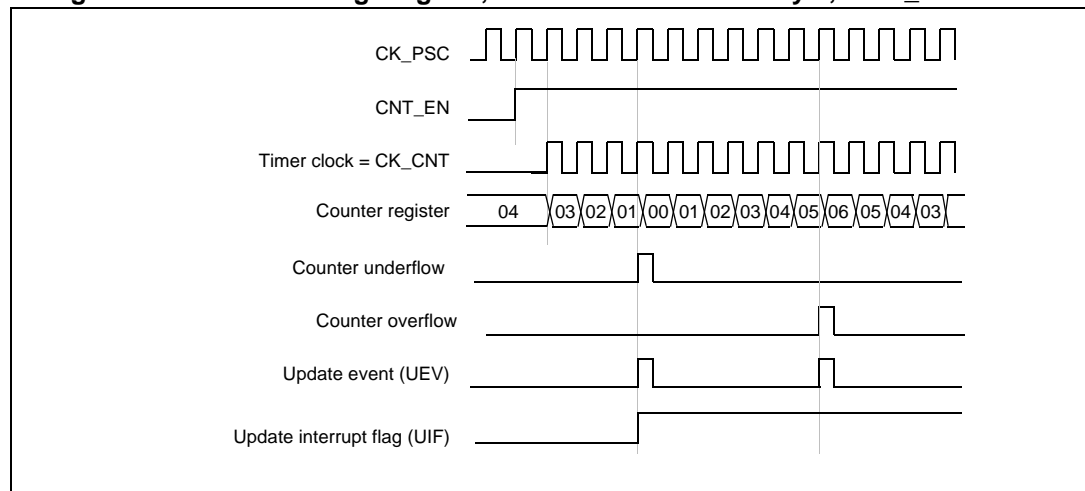
In addition, if the URS bit (update request selection) in TIMx\_CR1 register is set, setting the UG bit generates an UEV update event but without setting the UIF flag (thus no interrupt or DMA request is sent). This is to avoid generating both update and capture interrupts when clearing the counter on the capture event.

When an update event occurs, all the registers are updated and the update flag (UIF bit in TIMx\_SR register) is set (depending on the URS bit):

- The repetition counter is reloaded with the content of TIMx\_RCR register
- The buffer of the prescaler is reloaded with the preload value (content of the TIMx\_PSC register)
- The auto-reload active register is updated with the preload value (content of the TIMx\_ARR register). Note that if the update source is a counter overflow, the auto-reload is updated before the counter is reloaded, so that the next period is the expected one (the counter is loaded with the new value).

The following figures show some examples of the counter behavior for different clock frequencies.

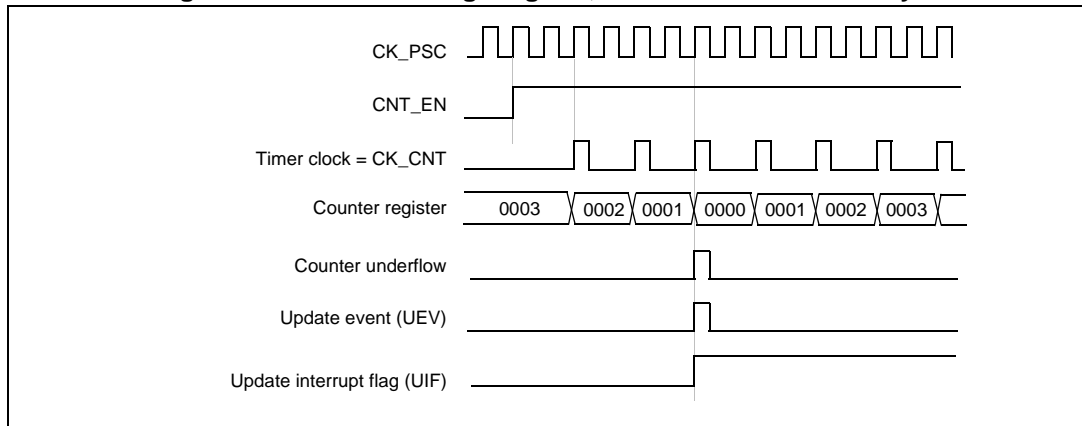
**Figure 53. Counter timing diagram, internal clock divided by 1, TIMx\_ARR = 0x6**



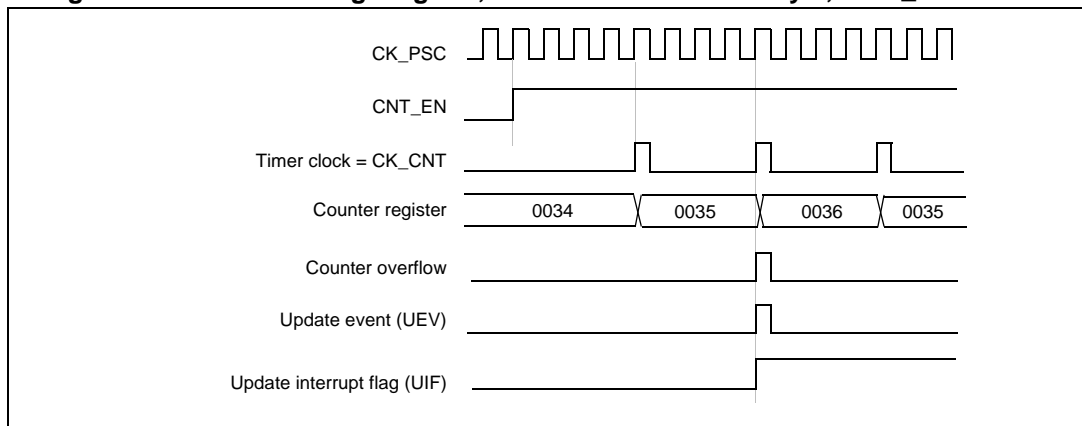
1. Here, center-aligned mode 1 is used (for more details refer to [Section 12.4: TIM1 registers on page 283](#)).



**Figure 54. Counter timing diagram, internal clock divided by 2**



**Figure 55. Counter timing diagram, internal clock divided by 4, TIMx\_ARR=0x36**



1. Center-aligned mode 2 or 3 is used with an UIF on overflow.

**Figure 56. Counter timing diagram, internal clock divided by N**

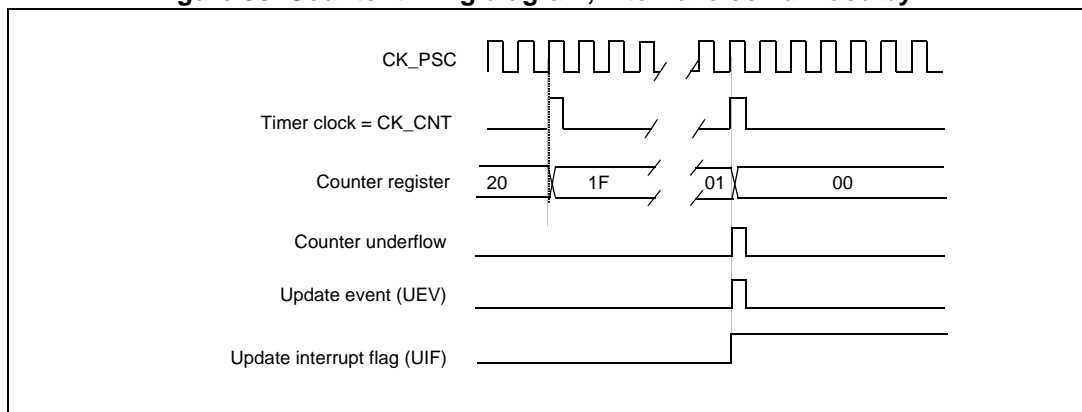


Figure 57. Counter timing diagram, update event with ARPE=1 (counter underflow)

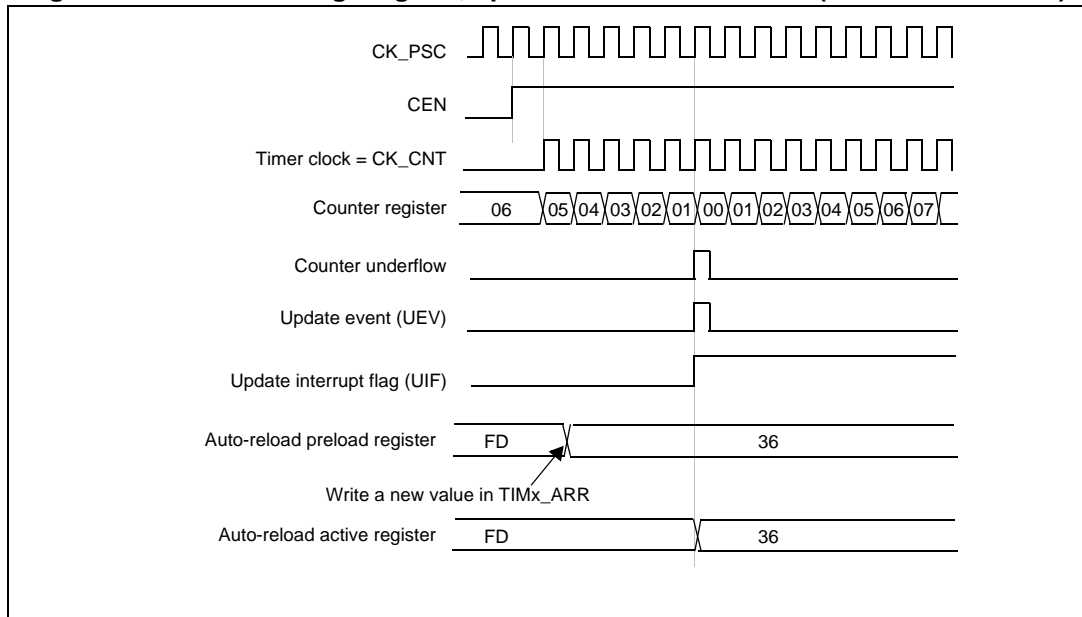
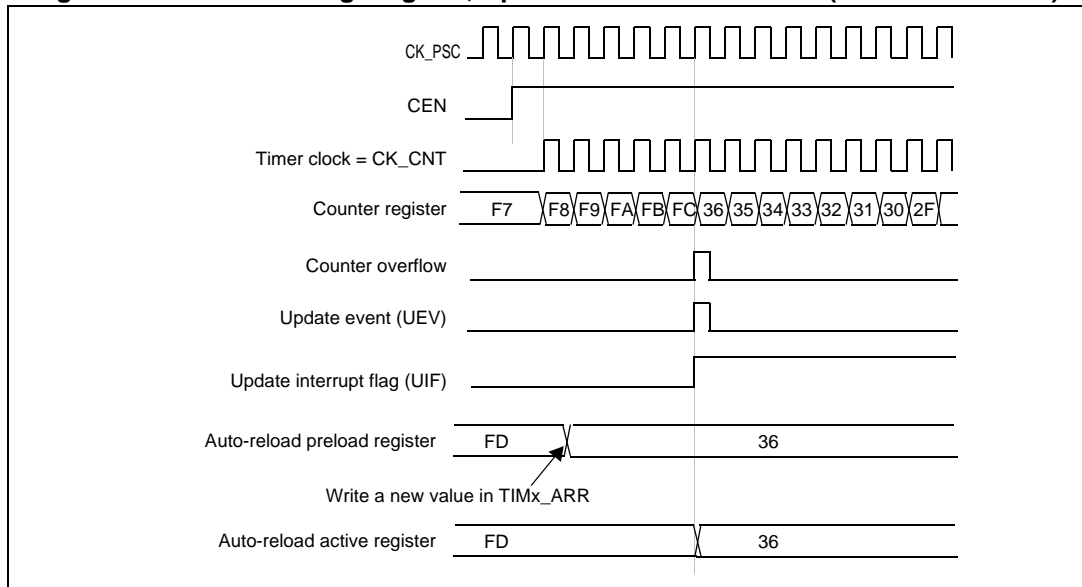


Figure 58. Counter timing diagram, Update event with ARPE=1 (counter overflow)



### 12.3.3 Repetition counter

*Section 12.3.1: Time-base unit* describes how the update event (UEV) is generated with respect to the counter overflows/underflows. It is actually generated only when the repetition counter has reached zero. This can be useful when generating PWM signals.

This means that data are transferred from the preload registers to the shadow registers (TIMx\_ARR auto-reload register, TIMx\_PSC prescaler register, but also TIMx\_CCRx capture/compare registers in compare mode) every N+1 counter overflows or underflows, where N is the value in the TIMx\_RCR repetition counter register.

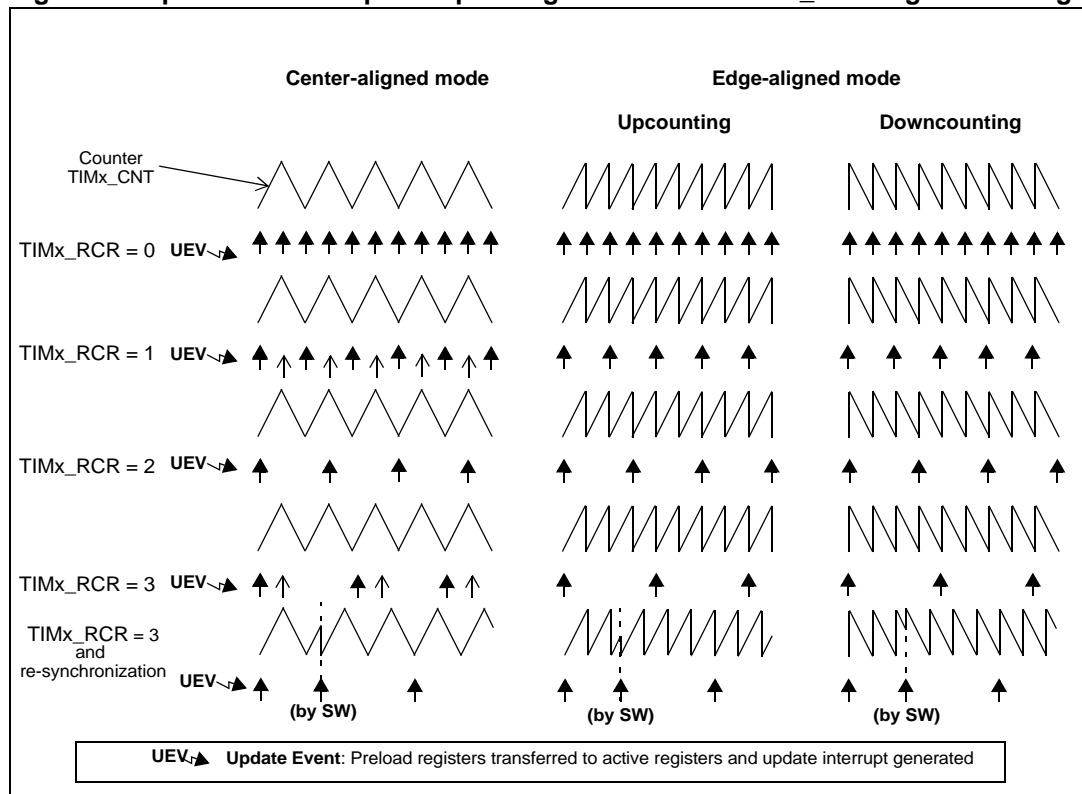
The repetition counter is decremented:

- At each counter overflow in upcounting mode,
- At each counter underflow in downcounting mode,
- At each counter overflow and at each counter underflow in center-aligned mode.  
Although this limits the maximum number of repetition to 128 PWM cycles, it makes it possible to update the duty cycle twice per PWM period. When refreshing compare registers only once per PWM period in center-aligned mode, maximum resolution is  $2xT_{ck}$ , due to the symmetry of the pattern.

The repetition counter is an auto-reload type; the repetition rate is maintained as defined by the TIMx\_RCR register value (refer to [Figure 59](#)). When the update event is generated by software (by setting the UG bit in TIMx\_EGR register) or by hardware through the slave mode controller, it occurs immediately whatever the value of the repetition counter is and the repetition counter is reloaded with the content of the TIMx\_RCR register.

In center-aligned mode, for odd values of RCR, the update event occurs either on the overflow or on the underflow depending on when the RCR register was written and when the counter was started. If the RCR was written before starting the counter, the UEV occurs on the overflow. If the RCR was written after starting the counter, the UEV occurs on the underflow. For example for RCR = 3, the UEV is generated on each 4th overflow or underflow event depending on when RCR was written.

**Figure 59. Update rate examples depending on mode and TIMx\_RCR register settings**



### 12.3.4 Clock selection

The counter clock can be provided by the following clock sources:

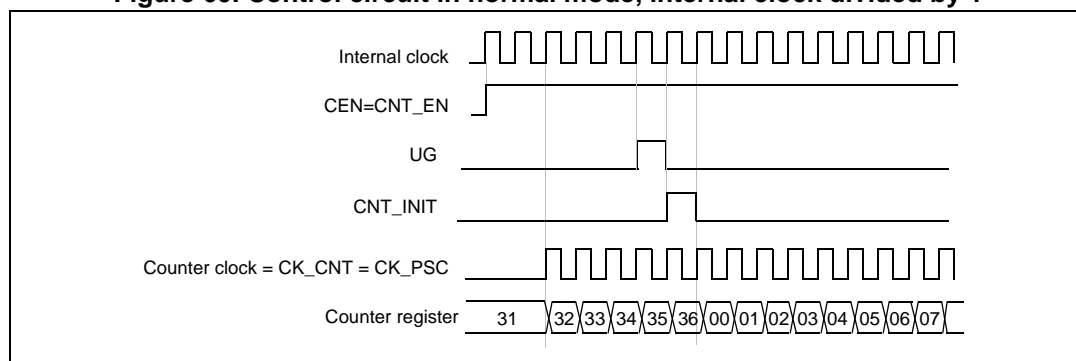
- Internal clock (CK\_INT)
- External clock mode1: external input pin
- External clock mode2: external trigger input ETR
- Internal trigger inputs (ITRx): using one timer as prescaler for another timer, for example, you can configure Timer 1 to act as a prescaler for Timer 2. Refer to [Using one timer as prescaler for another timer](#) for more details.

#### Internal clock source (CK\_INT)

If the slave mode controller is disabled (SMS=000), then the CEN, DIR (in the TIMx\_CR1 register) and UG bits (in the TIMx\_EGR register) are actual control bits and can be changed only by software (except UG which remains cleared automatically). As soon as the CEN bit is written to 1, the prescaler is clocked by the internal clock CK\_INT.

Figure 60 shows the behavior of the control circuit and the upcounter in normal mode, without prescaler.

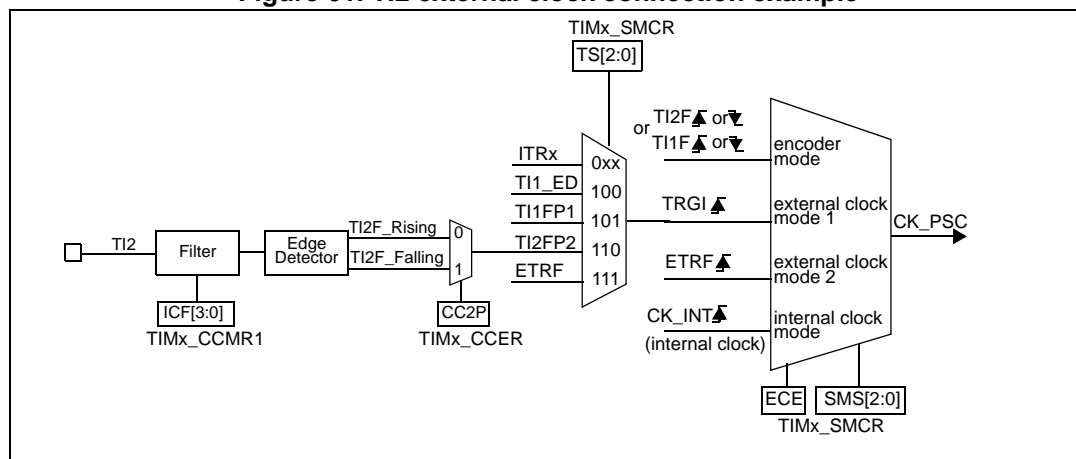
Figure 60. Control circuit in normal mode, internal clock divided by 1



#### External clock source mode 1

This mode is selected when SMS=111 in the TIMx\_SMCR register. The counter can count at each rising or falling edge on a selected input.

Figure 61. TI2 external clock connection example



For example, to configure the upcounter to count in response to a rising edge on the TI2 input, use the following procedure:

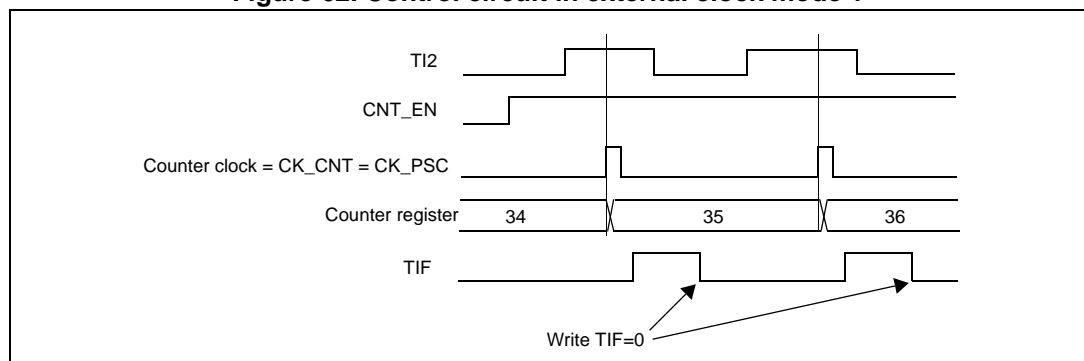
1. Configure channel 2 to detect rising edges on the TI2 input by writing CC2S = '01' in the TIMx\_CCMR1 register.
2. Configure the input filter duration by writing the IC2F[3:0] bits in the TIMx\_CCMR1 register (if no filter is needed, keep IC2F=0000).
3. Select rising edge polarity by writing CC2P=0 and CC2NP=0 in the TIMx\_CCER register.
4. Configure the timer in external clock mode 1 by writing SMS=111 in the TIMx\_SMCR register.
5. Select TI2 as the trigger input source by writing TS=110 in the TIMx\_SMCR register.
6. Enable the counter by writing CEN=1 in the TIMx\_CR1 register.

*Note:* The capture prescaler is not used for triggering, so you don't need to configure it.

When a rising edge occurs on TI2, the counter counts once and the TIF flag is set.

The delay between the rising edge on TI2 and the actual clock of the counter is due to the resynchronization circuit on TI2 input.

**Figure 62. Control circuit in external clock mode 1**



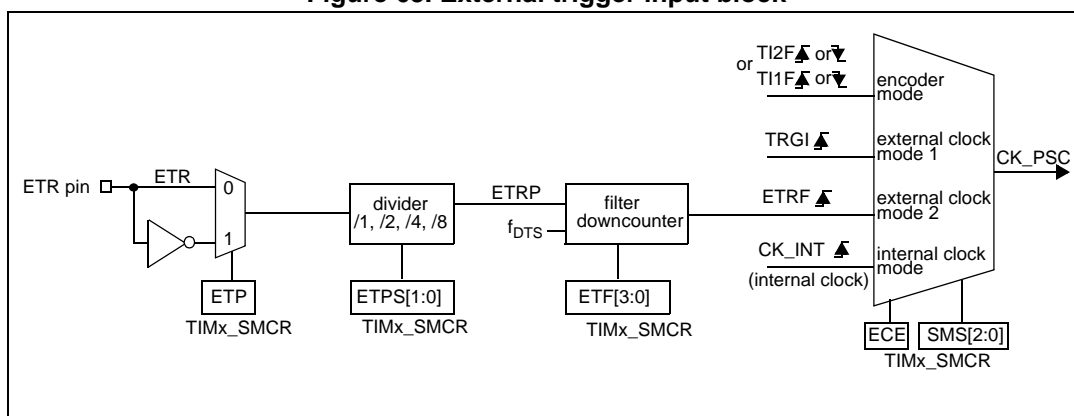
**External clock source mode 2**

This mode is selected by writing ECE=1 in the TIMx\_SMCR register.

The counter can count at each rising or falling edge on the external trigger input ETR.

[Figure 63](#) gives an overview of the external trigger input block.

Figure 63. External trigger input block



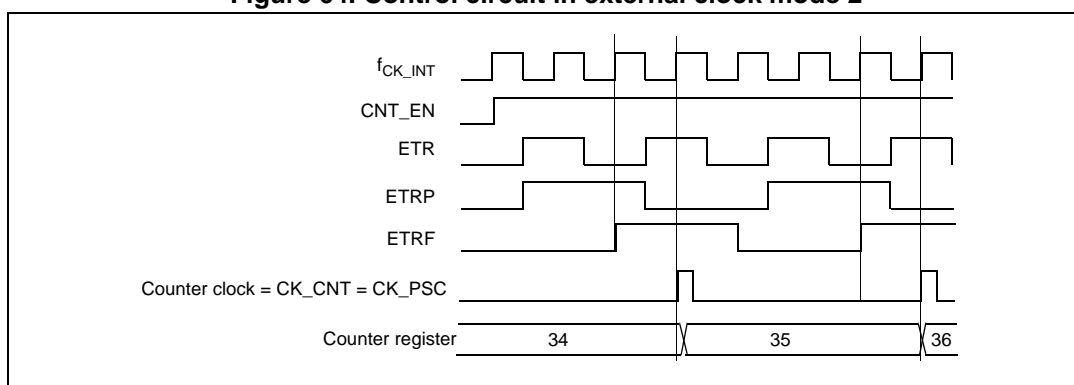
For example, to configure the upcounter to count each 2 rising edges on ETR, use the following procedure:

1. As no filter is needed in this example, write  $ETF[3:0]=0000$  in the  $TIMx\_SMCR$  register.
2. Set the prescaler by writing  $ETPS[1:0]=01$  in the  $TIMx\_SMCR$  register
3. Select rising edge detection on the ETR pin by writing  $ETP=0$  in the  $TIMx\_SMCR$  register
4. Enable external clock mode 2 by writing  $ECE=1$  in the  $TIMx\_SMCR$  register.
5. Enable the counter by writing  $CEN=1$  in the  $TIMx\_CR1$  register.

The counter counts once each 2 ETR rising edges.

The delay between the rising edge on ETR and the actual clock of the counter is due to the resynchronization circuit on the ETRP signal.

Figure 64. Control circuit in external clock mode 2



### 12.3.5 Capture/compare channels

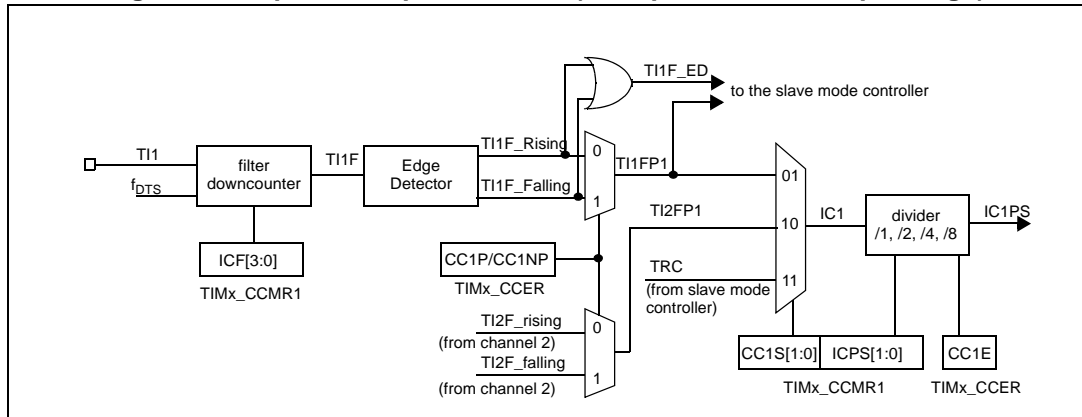
Each Capture/Compare channel is built around a capture/compare register (including a shadow register), a input stage for capture (with digital filter, multiplexing and prescaler) and an output stage (with comparator and output control).

[Figure 65](#) to [Figure 68](#) give an overview of one Capture/Compare channel.

The input stage samples the corresponding  $Tix$  input to generate a filtered signal  $TixF$ . Then, an edge detector with polarity selection generates a signal ( $TixFPx$ ) which can be

used as trigger input by the slave mode controller or as the capture command. It is prescaled before the capture register (ICxPS).

**Figure 65. Capture/compare channel (example: channel 1 input stage)**



The output stage generates an intermediate waveform which is then used for reference: OCxRef (active high). The polarity acts at the end of the chain.

**Figure 66. Capture/compare channel 1 main circuit**

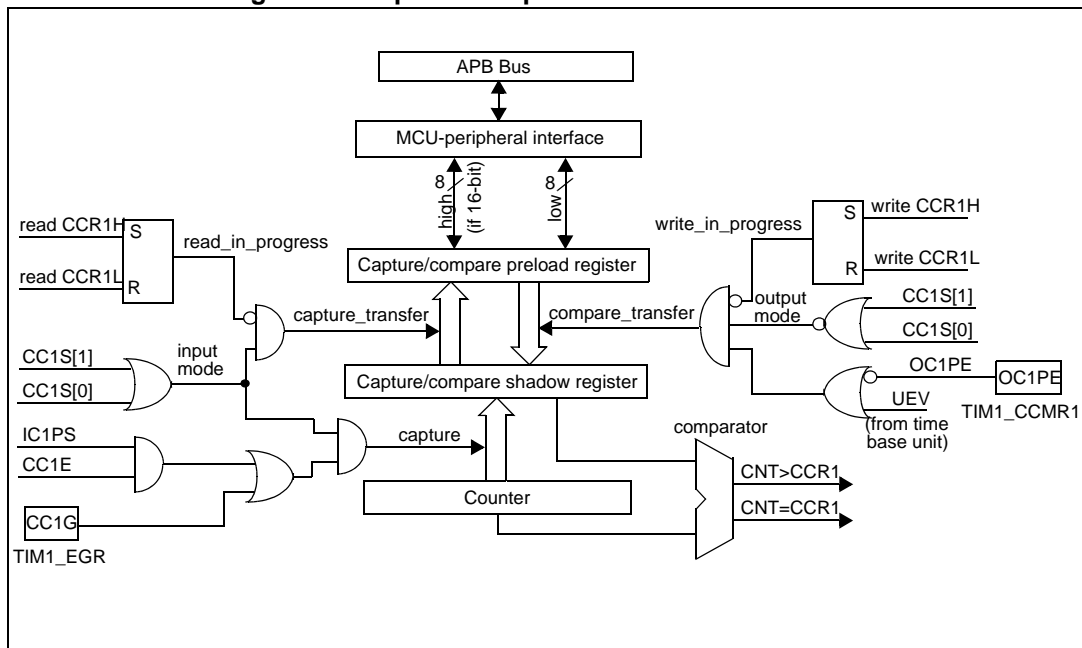


Figure 67. Output stage of capture/compare channel (channel 1 to 3)

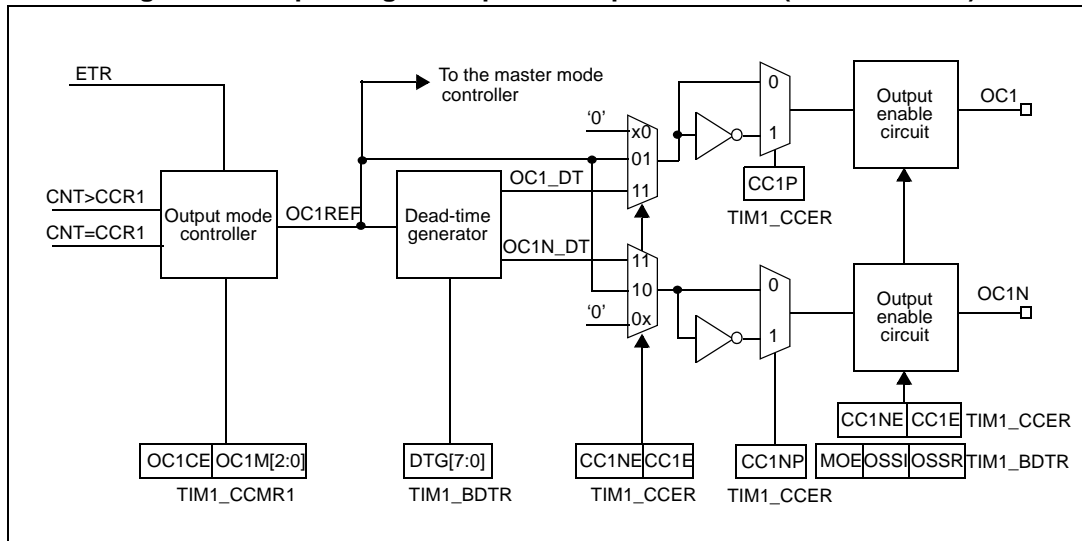
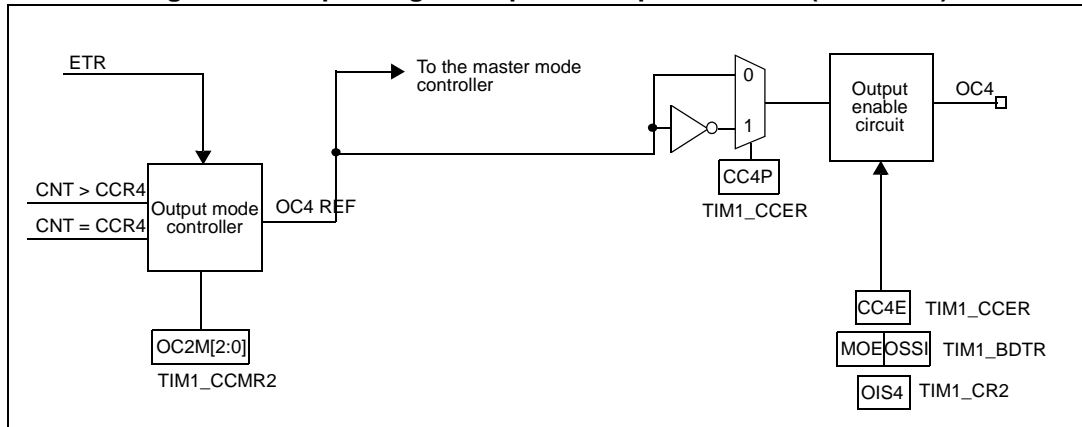


Figure 68. Output stage of capture/compare channel (channel 4)



The capture/compare block is made of one preload register and one shadow register. Write and read always access the preload register.

In capture mode, captures are actually done in the shadow register, which is copied into the preload register.

In compare mode, the content of the preload register is copied into the shadow register which is compared to the counter.

### 12.3.6 Input capture mode

In Input capture mode, the Capture/Compare Registers (TIMx\_CCRx) are used to latch the value of the counter after a transition detected by the corresponding ICx signal. When a capture occurs, the corresponding CCXIF flag (TIMx\_SR register) is set and an interrupt or a DMA request can be sent if they are enabled. If a capture occurs while the CCxIF flag was already high, then the over-capture flag CCxOF (TIMx\_SR register) is set. CCxIF can be cleared by software by writing it to '0' or by reading the captured data stored in the TIMx\_CCRx register. CCxOF is cleared when you write it to '0'.



The following example shows how to capture the counter value in TIMx\_CCR1 when TI1 input rises. To do this, use the following procedure:

- Select the active input: TIMx\_CCR1 must be linked to the TI1 input, so write the CC1S bits to 01 in the TIMx\_CCMR1 register. As soon as CC1S becomes different from 00, the channel is configured in input and the TIMx\_CCR1 register becomes read-only.
- Program the input filter duration you need with respect to the signal you connect to the timer (by programming ICx F bits in the TIMx\_CCMRx register if the input is a TIx input). Let's imagine that, when toggling, the input signal is not stable during at most 5 internal clock cycles. We must program a filter duration longer than these 5 clock cycles. We can validate a transition on TI1 when 8 consecutive samples with the new level have been detected (sampled at  $f_{DTS}$  frequency). Then write IC1F bits to 0011 in the TIMx\_CCMR1 register.
- Select the edge of the active transition on the TI1 channel by writing CC1P and CC1NP bits to 0 in the TIMx\_CCER register (rising edge in this case).
- Program the input prescaler. In our example, we wish the capture to be performed at each valid transition, so the prescaler is disabled (write IC1PS bits to '00' in the TIMx\_CCMR1 register).
- Enable capture from the counter into the capture register by setting the CC1E bit in the TIMx\_CCER register.
- If needed, enable the related interrupt request by setting the CC1IE bit in the TIMx\_DIER register, and/or the DMA request by setting the CC1DE bit in the TIMx\_DIER register.

When an input capture occurs:

- The TIMx\_CCR1 register gets the value of the counter on the active transition.
- CC1IF flag is set (interrupt flag). CC1OF is also set if at least two consecutive captures occurred whereas the flag was not cleared.
- An interrupt is generated depending on the CC1IE bit.
- A DMA request is generated depending on the CC1DE bit.

In order to handle the overcapture, it is recommended to read the data before the overcapture flag. This is to avoid missing an overcapture which could happen after reading the flag and before reading the data.

*Note:* IC interrupt and/or DMA requests can be generated by software by setting the corresponding CCxG bit in the TIMx\_EGR register.

### 12.3.7 PWM input mode

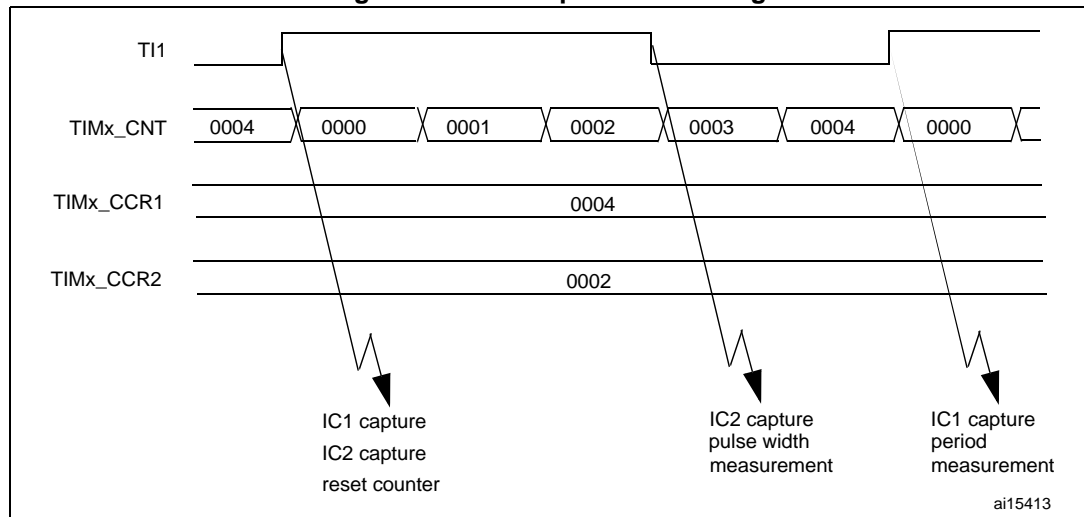
This mode is a particular case of input capture mode. The procedure is the same except:

- Two ICx signals are mapped on the same TIx input.
- These 2 ICx signals are active on edges with opposite polarity.
- One of the two TIxFP signals is selected as trigger input and the slave mode controller is configured in reset mode.

For example, you can measure the period (in TIMx\_CCR1 register) and the duty cycle (in TIMx\_CCR2 register) of the PWM applied on TI1 using the following procedure (depending on CK\_INT frequency and prescaler value):

- Select the active input for TIMx\_CCR1: write the CC1S bits to 01 in the TIMx\_CCMR1 register (TI1 selected).
- Select the active polarity for TI1FP1 (used both for capture in TIMx\_CCR1 and counter clear): write the CC1P and CC1NP bits to '0' (active on rising edge).
- Select the active input for TIMx\_CCR2: write the CC2S bits to 10 in the TIMx\_CCMR1 register (TI1 selected).
- Select the active polarity for TI1FP2 (used for capture in TIMx\_CCR2): write the CC2P and CC2NP bits to '1' (active on falling edge).
- Select the valid trigger input: write the TS bits to 101 in the TIMx\_SMCR register (TI1FP1 selected).
- Configure the slave mode controller in reset mode: write the SMS bits to 100 in the TIMx\_SMCR register.
- Enable the captures: write the CC1E and CC2E bits to '1' in the TIMx\_CCER register.

Figure 69. PWM input mode timing



### 12.3.8 Forced output mode

In output mode (CCxS bits = 00 in the TIMx\_CCMRx register), each output compare signal (OCxREF and then OCx/OCxN) can be forced to active or inactive level directly by software, independently of any comparison between the output compare register and the counter.

To force an output compare signal (OCxREF/OCx) to its active level, you just need to write 101 in the OCxM bits in the corresponding TIMx\_CCMRx register. Thus OCxREF is forced high (OCxREF is always active high) and OCx get opposite value to CCxP polarity bit.

For example: CCxP=0 (OCx active high) => OCx is forced to high level.

The OCxREF signal can be forced low by writing the OCxM bits to 100 in the TIMx\_CCMRx register.

Anyway, the comparison between the TIMx\_CCRx shadow register and the counter is still performed and allows the flag to be set. Interrupt and DMA requests can be sent accordingly. This is described in the output compare mode section below.

### 12.3.9 Output compare mode

This function is used to control an output waveform or indicating when a period of time has elapsed.

When a match is found between the capture/compare register and the counter, the output compare function:

- Assigns the corresponding output pin to a programmable value defined by the output compare mode (OCxM bits in the TIMx\_CCMRx register) and the output polarity (CCxP bit in the TIMx\_CCER register). The output pin can keep its level (OCxM=000), be set active (OCxM=001), be set inactive (OCxM=010) or can toggle (OCxM=011) on match.
- Sets a flag in the interrupt status register (CCxIF bit in the TIMx\_SR register).
- Generates an interrupt if the corresponding interrupt mask is set (CCXIE bit in the TIMx\_DIER register).
- Sends a DMA request if the corresponding enable bit is set (CCxDE bit in the TIMx\_DIER register, CCDS bit in the TIMx\_CR2 register for the DMA request selection).

The TIMx\_CCRx registers can be programmed with or without preload registers using the OCxPE bit in the TIMx\_CCMRx register.

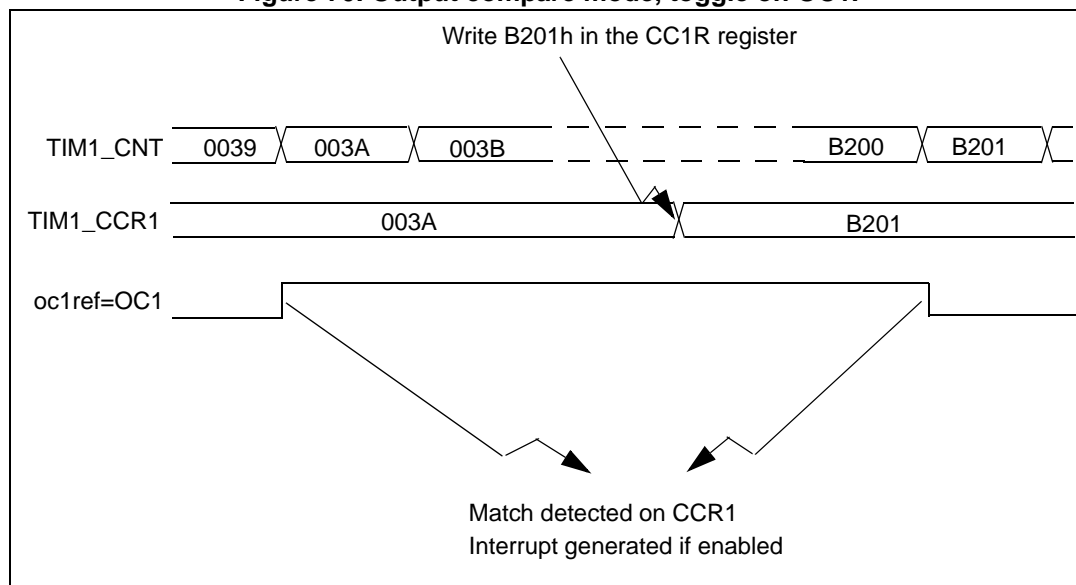
In output compare mode, the update event UEV has no effect on OCxREF and OCx output. The timing resolution is one count of the counter. Output compare mode can also be used to output a single pulse (in One Pulse mode).

Procedure:

1. Select the counter clock (internal, external, prescaler).
2. Write the desired data in the TIMx\_ARR and TIMx\_CCRx registers.
3. Set the CCxIE bit if an interrupt request is to be generated.
4. Select the output mode. For example:
  - Write OCxM = 011 to toggle OCx output pin when CNT matches CCRx
  - Write OCxPE = 0 to disable preload register
  - Write CCxP = 0 to select active high polarity
  - Write CCxE = 1 to enable the output
5. Enable the counter by setting the CEN bit in the TIMx\_CR1 register.

The TIMx\_CCRx register can be updated at any time by software to control the output waveform, provided that the preload register is not enabled (OCxPE='0', else TIMx\_CCRx shadow register is updated only at the next update event UEV). An example is given in [Figure 70](#).

**Figure 70. Output compare mode, toggle on OC1.**



### 12.3.10 PWM mode

Pulse Width Modulation mode allows you to generate a signal with a frequency determined by the value of the TIMx\_ARR register and a duty cycle determined by the value of the TIMx\_CCRx register.

The PWM mode can be selected independently on each channel (one PWM per OCx output) by writing '110' (PWM mode 1) or '111' (PWM mode 2) in the OCxM bits in the TIMx\_CCMRx register. You must enable the corresponding preload register by setting the OCxPE bit in the TIMx\_CCMRx register, and eventually the auto-reload preload register (in upcounting or center-aligned modes) by setting the ARPE bit in the TIMx\_CR1 register.

As the preload registers are transferred to the shadow registers only when an update event occurs, before starting the counter, you have to initialize all the registers by setting the UG bit in the TIMx\_EGR register.

OCx polarity is software programmable using the CCxP bit in the TIMx\_CCER register. It can be programmed as active high or active low. OCx output is enabled by a combination of the CCxE, CCxNE, MOE, OSSI and OSSR bits (TIMx\_CCER and TIMx\_BDTR registers). Refer to the TIMx\_CCER register description for more details.

In PWM mode (1 or 2), TIMx\_CNT and TIMx\_CCRx are always compared to determine whether  $TIMx\_CCRx \leq TIMx\_CNT$  or  $TIMx\_CNT \leq TIMx\_CCRx$  (depending on the direction of the counter).

The timer is able to generate PWM in edge-aligned mode or center-aligned mode depending on the CMS bits in the TIMx\_CR1 register.

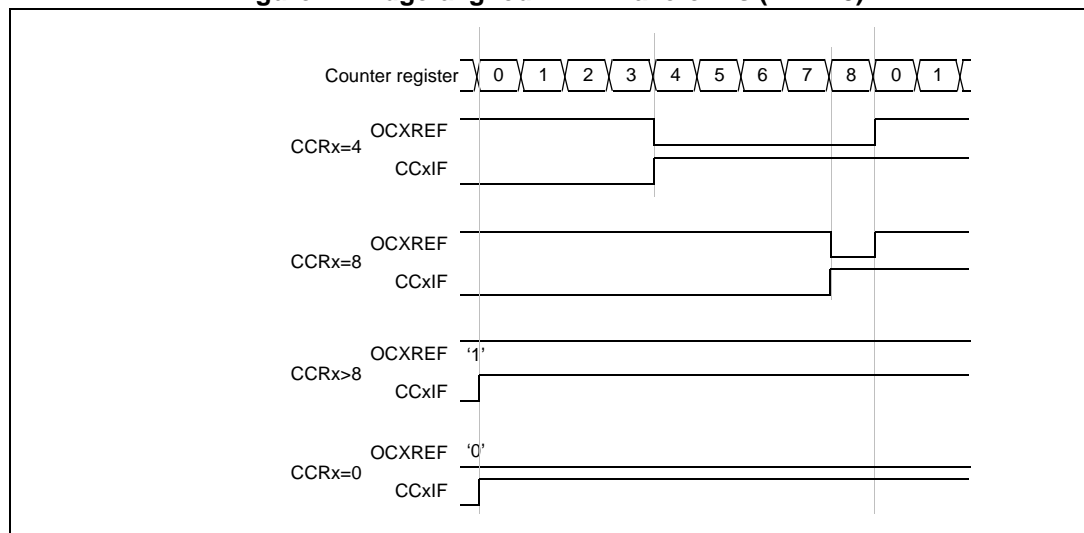
**PWM edge-aligned mode**

- Upcounting configuration

Upcounting is active when the DIR bit in the TIMx\_CR1 register is low. Refer to [Section : Upcounting mode on page 245](#).

In the following example, we consider PWM mode 1. The reference PWM signal OCxREF is high as long as  $TIMx\_CNT < TIMx\_CCRx$  else it becomes low. If the compare value in TIMx\_CCRx is greater than the auto-reload value (in TIMx\_ARR) then OCxREF is held at '1'. If the compare value is 0 then OCxRef is held at '0'. [Figure 71](#) shows some edge-aligned PWM waveforms in an example where  $TIMx\_ARR=8$ .

**Figure 71. Edge-aligned PWM waveforms (ARR=8)**



- Downcounting configuration

Downcounting is active when DIR bit in TIMx\_CR1 register is high. Refer to [Section : Downcounting mode on page 248](#)

In PWM mode 1, the reference signal OCxRef is low as long as  $TIMx\_CNT > TIMx\_CCRx$  else it becomes high. If the compare value in TIMx\_CCRx is greater than the auto-reload value in TIMx\_ARR, then OCxREF is held at '1'. 0% PWM is not possible in this mode.

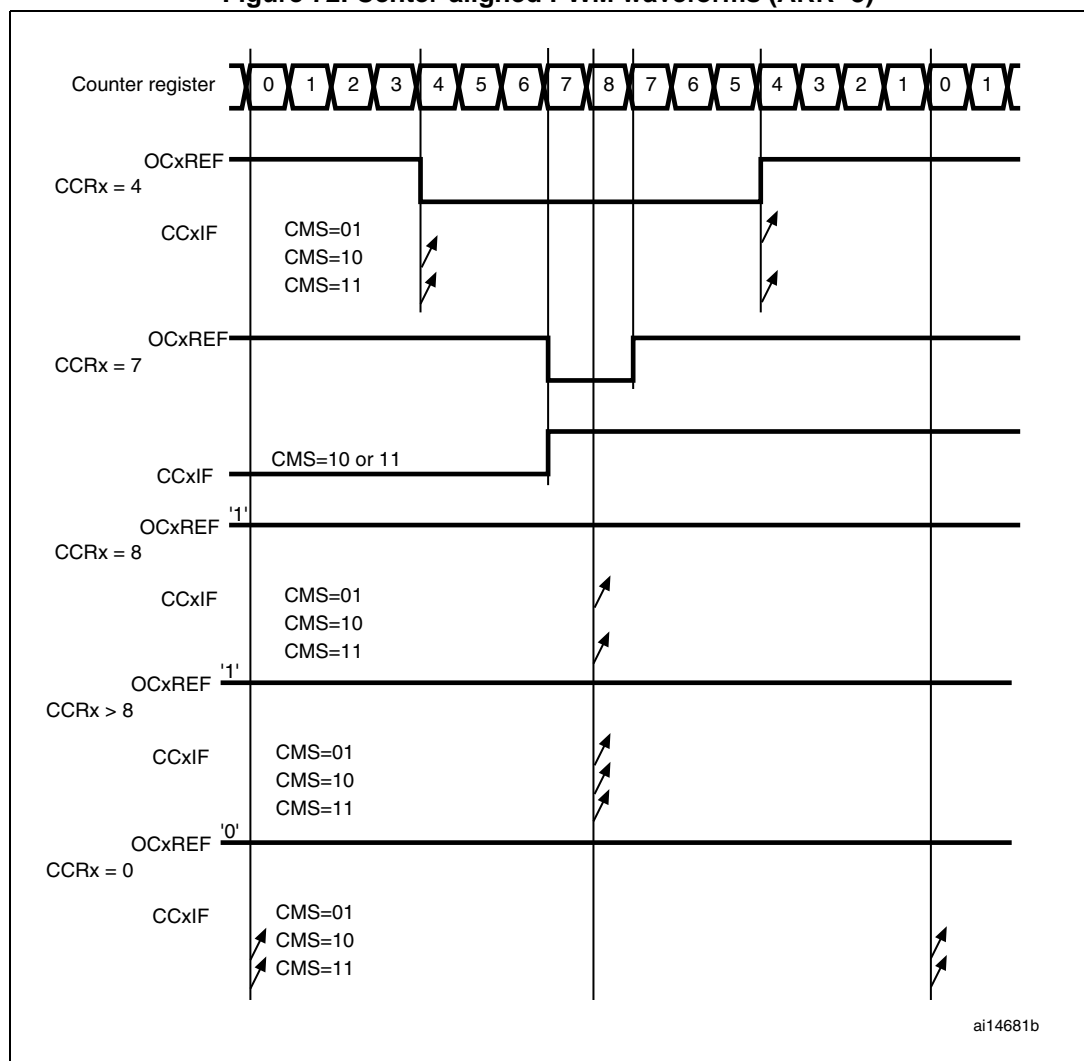
**PWM center-aligned mode**

Center-aligned mode is active when the CMS bits in TIMx\_CR1 register are different from '00' (all the remaining configurations having the same effect on the OCxRef/OCx signals). The compare flag is set when the counter counts up, when it counts down or both when it counts up and down depending on the CMS bits configuration. The direction bit (DIR) in the TIMx\_CR1 register is updated by hardware and must not be changed by software. Refer to [Section : Center-aligned mode \(up/down counting\) on page 250](#).

Figure 72 shows some center-aligned PWM waveforms in an example where:

- TIMx\_ARR=8,
- PWM mode is the PWM mode 1,
- The flag is set when the counter counts down corresponding to the center-aligned mode 1 selected for CMS=01 in TIMx\_CR1 register.

**Figure 72. Center-aligned PWM waveforms (ARR=8)**



Hints on using center-aligned mode:

- When starting in center-aligned mode, the current up-down configuration is used. It means that the counter counts up or down depending on the value written in the DIR bit in the TIMx\_CR1 register. Moreover, the DIR and CMS bits must not be changed at the same time by the software.
- Writing to the counter while running in center-aligned mode is not recommended as it can lead to unexpected results. In particular:
  - The direction is not updated if you write a value in the counter that is greater than the auto-reload value ( $TIMx\_CNT > TIMx\_ARR$ ). For example, if the counter was counting up, it continues to count up.
  - The direction is updated if you write 0 or write the TIMx\_ARR value in the counter but no Update Event UEV is generated.
- The safest way to use center-aligned mode is to generate an update by software (setting the UG bit in the TIMx\_EGR register) just before starting the counter and not to write the counter while it is running.

### 12.3.11 Complementary outputs and dead-time insertion

The advanced-control timers (TIM1) can output two complementary signals and manage the switching-off and the switching-on instants of the outputs.

This time is generally known as dead-time and you have to adjust it depending on the devices you have connected to the outputs and their characteristics (intrinsic delays of level-shifters, delays due to power switches...)

You can select the polarity of the outputs (main output OCx or complementary OCxN) independently for each output. This is done by writing to the CCxP and CCxNP bits in the TIMx\_CCER register.

The complementary signals OCx and OCxN are activated by a combination of several control bits: the CCxE and CCxNE bits in the TIMx\_CCER register and the MOE, OISx, OISxN, OSSI and OSSR bits in the TIMx\_BDTR and TIMx\_CR2 registers. Refer to [Table 51: Output control bits for complementary OCx and OCxN channels with break feature on page 301](#) for more details. In particular, the dead-time is activated when switching to the IDLE state (MOE falling down to 0).

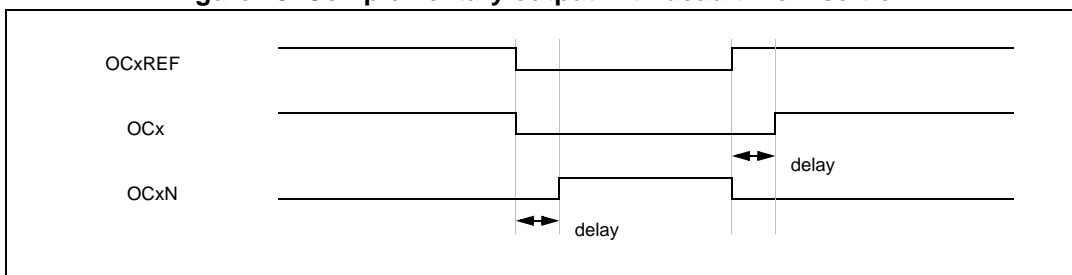
Dead-time insertion is enabled by setting both CCxE and CCxNE bits, and the MOE bit if the break circuit is present. DTG[7:0] bits of the TIMx\_BDTR register are used to control the dead-time generation for all channels. From a reference waveform OCxREF, it generates 2 outputs OCx and OCxN. If OCx and OCxN are active high:

- The OCx output signal is the same as the reference signal except for the rising edge, which is delayed relative to the reference rising edge.
- The OCxN output signal is the opposite of the reference signal except for the rising edge, which is delayed relative to the reference falling edge.

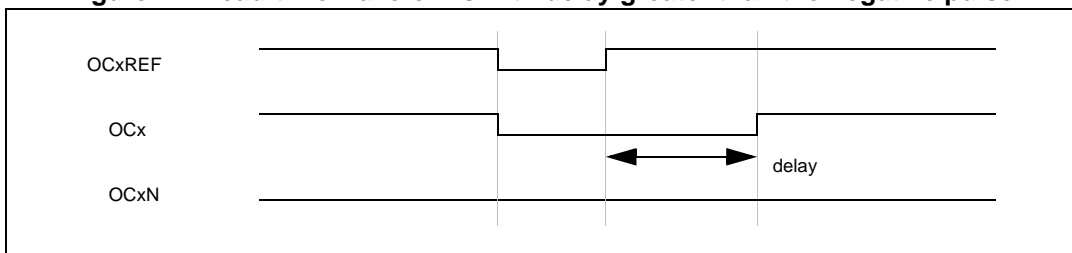
If the delay is greater than the width of the active output (OCx or OCxN) then the corresponding pulse is not generated.

The following figures show the relationships between the output signals of the dead-time generator and the reference signal OCxREF. (we suppose CCxP=0, CCxNP=0, MOE=1, CCxE=1 and CCxNE=1 in these examples)

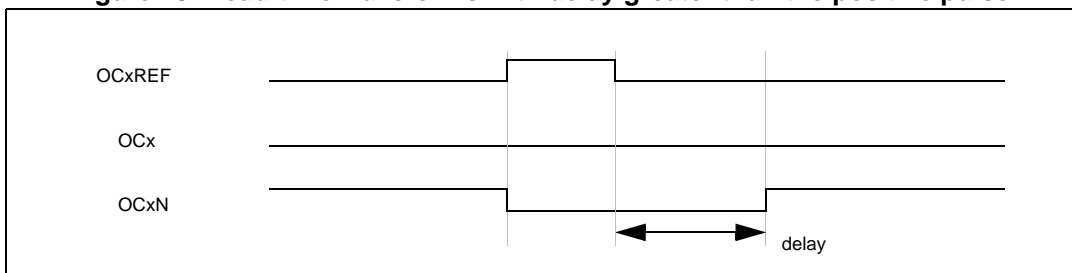
**Figure 73. Complementary output with dead-time insertion.**



**Figure 74. Dead-time waveforms with delay greater than the negative pulse.**



**Figure 75. Dead-time waveforms with delay greater than the positive pulse.**



The dead-time delay is the same for each of the channels and is programmable with the DTG bits in the TIMx\_BDTR register. Refer to [Section 12.4.18: TIM1 break and dead-time register \(TIMx\\_BDTR\) on page 305](#) for delay calculation.

**Re-directing OCxREF to OCx or OCxN**

In output mode (forced, output compare or PWM), OCxREF can be re-directed to the OCx output or to OCxN output by configuring the CCxE and CCxNE bits in the TIMx\_CCER register.

This allows you to send a specific waveform (such as PWM or static active level) on one output while the complementary remains at its inactive level. Other alternative possibilities are to have both outputs at inactive level or both outputs active and complementary with dead-time.

*Note: When only OCxN is enabled (CCxE=0, CCxNE=1), it is not complemented and becomes active as soon as OCxREF is high. For example, if CCxNP=0 then OCxN=OCxRef. On the other hand, when both OCx and OCxN are enabled (CCxE=CCxNE=1) OCx becomes active when OCxREF is high whereas OCxN is complemented and becomes active when OCxREF is low.*



### 12.3.12 Using the break function

When using the break function, the output enable signals and inactive levels are modified according to additional control bits (MOE, OSSI and OSSR bits in the TIMx\_BDTR register, OISx and OISxN bits in the TIMx\_CR2 register). In any case, the OCx and OCxN outputs cannot be set both to active level at a given time. Refer to [Table 51: Output control bits for complementary OCx and OCxN channels with break feature on page 301](#) for more details.

The break source can be either the break input pin or a clock failure event, generated by the Clock Security System (CSS), from the Reset Clock Controller. For further information on the Clock Security System, refer to [Section 6.2.7: Clock security system \(CSS\)](#).

When exiting from reset, the break circuit is disabled and the MOE bit is low. You can enable the break function by setting the BKE bit in the TIMx\_BDTR register. The break input polarity can be selected by configuring the BKP bit in the same register. BKE and BKP can be modified at the same time. When the BKE and BKP bits are written, a delay of 1 APB clock cycle is applied before the writing is effective. Consequently, it is necessary to wait 1 APB clock period to correctly read back the bit after the write operation.

Because MOE falling edge can be asynchronous, a resynchronization circuit has been inserted between the actual signal (acting on the outputs) and the synchronous control bit (accessed in the TIMx\_BDTR register). It results in some delays between the asynchronous and the synchronous signals. In particular, if you write MOE to 1 whereas it was low, you must insert a delay (dummy instruction) before reading it correctly. This is because you write the asynchronous signal and read the synchronous signal.

When a break occurs (selected level on the break input):

- The MOE bit is cleared asynchronously, putting the outputs in inactive state, idle state or in reset state (selected by the OSSI bit). This feature functions even if the MCU oscillator is off.
- Each output channel is driven with the level programmed in the OISx bit in the TIMx\_CR2 register as soon as MOE=0. If OSSI=0 then the timer releases the enable output else the enable output remains high.
- When complementary outputs are used:
  - The outputs are first put in reset state inactive state (depending on the polarity). This is done asynchronously so that it works even if no clock is provided to the timer.
  - If the timer clock is still present, then the dead-time generator is reactivated in order to drive the outputs with the level programmed in the OISx and OISxN bits after a dead-time. Even in this case, OCx and OCxN cannot be driven to their active level together. Note that because of the resynchronization on MOE, the dead-time duration is a bit longer than usual (around 2 ck\_tim clock cycles).
  - If OSSI=0 then the timer releases the enable outputs else the enable outputs remain or become high as soon as one of the CCxE or CCxNE bits is high.
- The break status flag (BIF bit in the TIMx\_SR register) is set. An interrupt can be generated if the BIE bit in the TIMx\_DIER register is set. A DMA request can be sent if the BDE bit in the TIMx\_DIER register is set.
- If the AOE bit in the TIMx\_BDTR register is set, the MOE bit is automatically set again at the next update event UEV. This can be used to perform a regulation, for instance. Else, MOE remains low until you write it to '1' again. In this case, it can be used for security and you can connect the break input to an alarm from power drivers, thermal sensors or any security components.

*Note:* The break inputs is acting on level. Thus, the MOE cannot be set while the break input is active (neither automatically nor by software). In the meantime, the status flag BIF cannot be cleared.

The break can be generated by the BRK input which has a programmable polarity and an enable bit BKE in the TIMx\_BDTR Register.

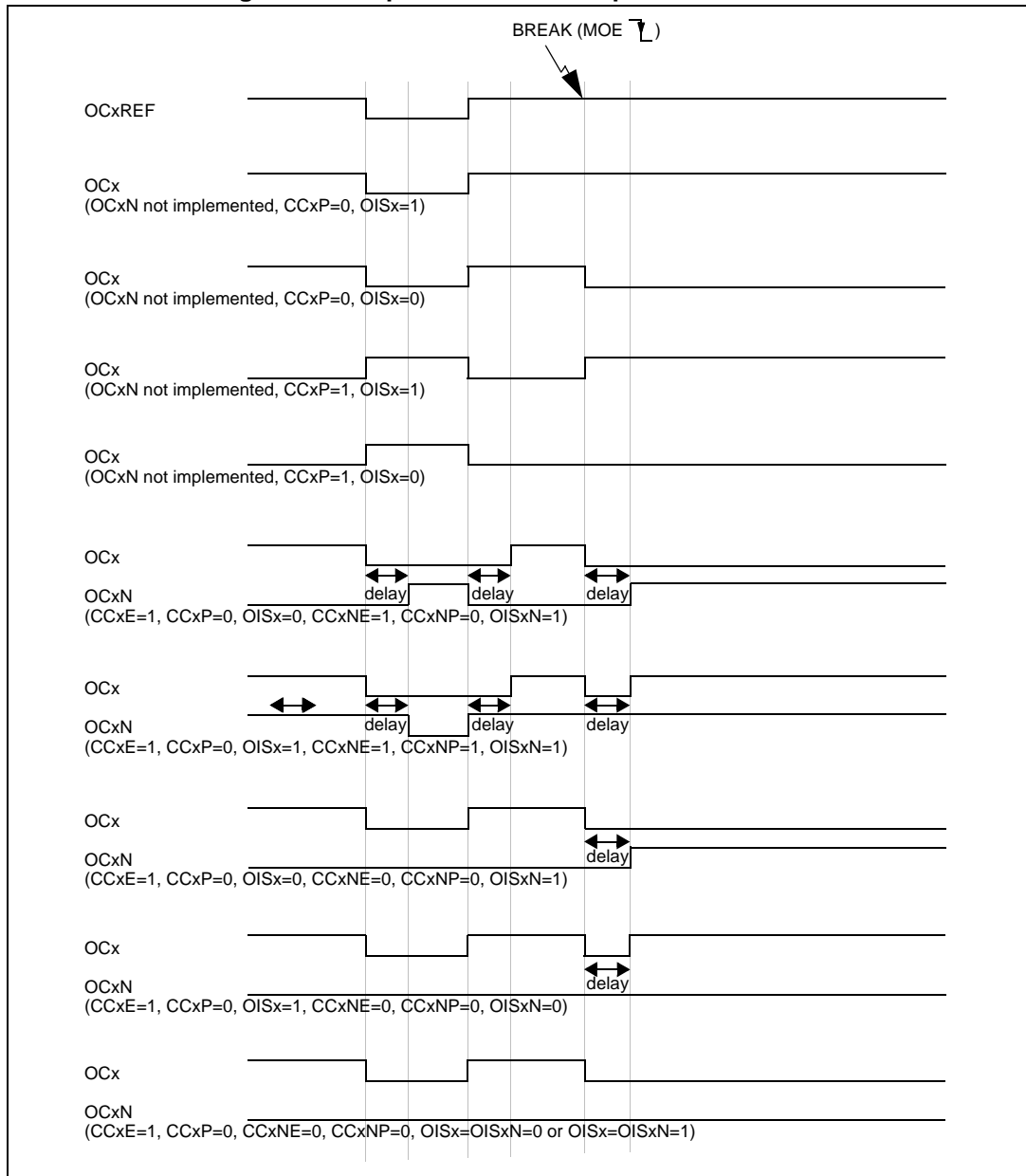
There are two solutions to generate a break:

- By using the BRK input which has a programmable polarity and an enable bit BKE in the TIMx\_BDTR register
- By software through the BG bit of the TIMx\_EGR register.

In addition to the break input and the output management, a write protection has been implemented inside the break circuit to safeguard the application. It allows you to freeze the configuration of several parameters (dead-time duration, OCx/OCxN polarities and state when disabled, OCxM configurations, break enable and polarity). You can choose from 3 levels of protection selected by the LOCK bits in the TIMx\_BDTR register. Refer to [Section 12.4.18: TIM1 break and dead-time register \(TIMx\\_BDTR\) on page 305](#). The LOCK bits can be written only once after an MCU reset.

[Figure 76](#) shows an example of behavior of the outputs in response to a break.

Figure 76. Output behavior in response to a break.



### 12.3.13 Clearing the OCxREF signal on an external event

The OCxREF signal for a given channel can be driven Low by applying a High level to the ETRF input (OCxCE enable bit of the corresponding TIMx\_CCMRx register set to '1'). The OCxREF signal remains Low until the next update event, UEV, occurs.

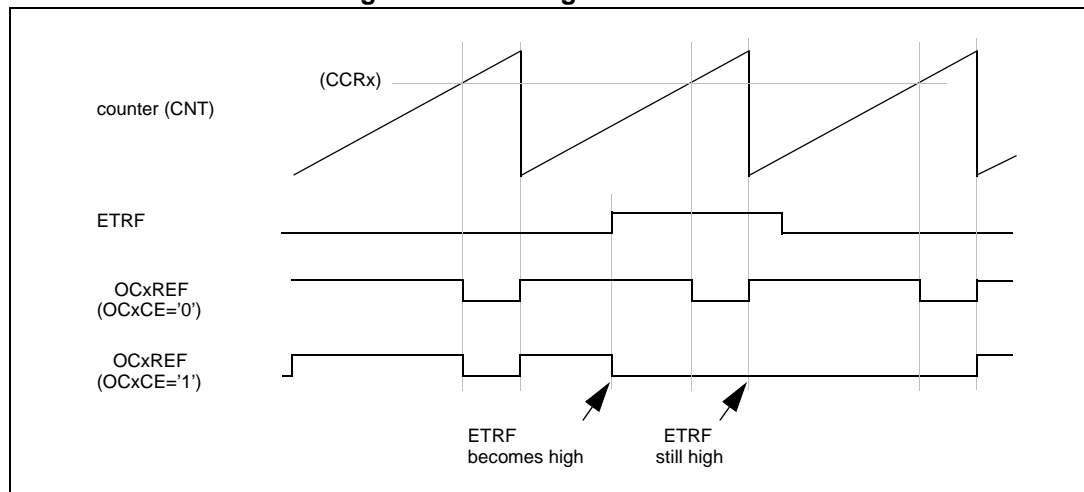
This function can only be used in output compare and PWM modes, and does not work in forced mode.

For example, the ETR signal can be connected to the output of a comparator to be used for current handling. In this case, the ETR must be configured as follow:

1. The External Trigger Prescaler should be kept off: bits ETPS[1:0] of the TIMx\_SMCR register set to '00'.
2. The external clock mode 2 must be disabled: bit ECE of the TIMx\_SMCR register set to '0'.
3. The External Trigger Polarity (ETP) and the External Trigger Filter (ETF) can be configured according to the user needs.

Figure 77 shows the behavior of the OCxREF signal when the ETRF Input becomes High, for both values of the enable bit OCxCE. In this example, the timer TIMx is programmed in PWM mode.

Figure 77. Clearing TIMx OCxREF



Note: In case of a PWM with a 100% duty cycle (if  $CCR_x > ARR$ ), then OCxREF is enabled again at the next counter overflow.

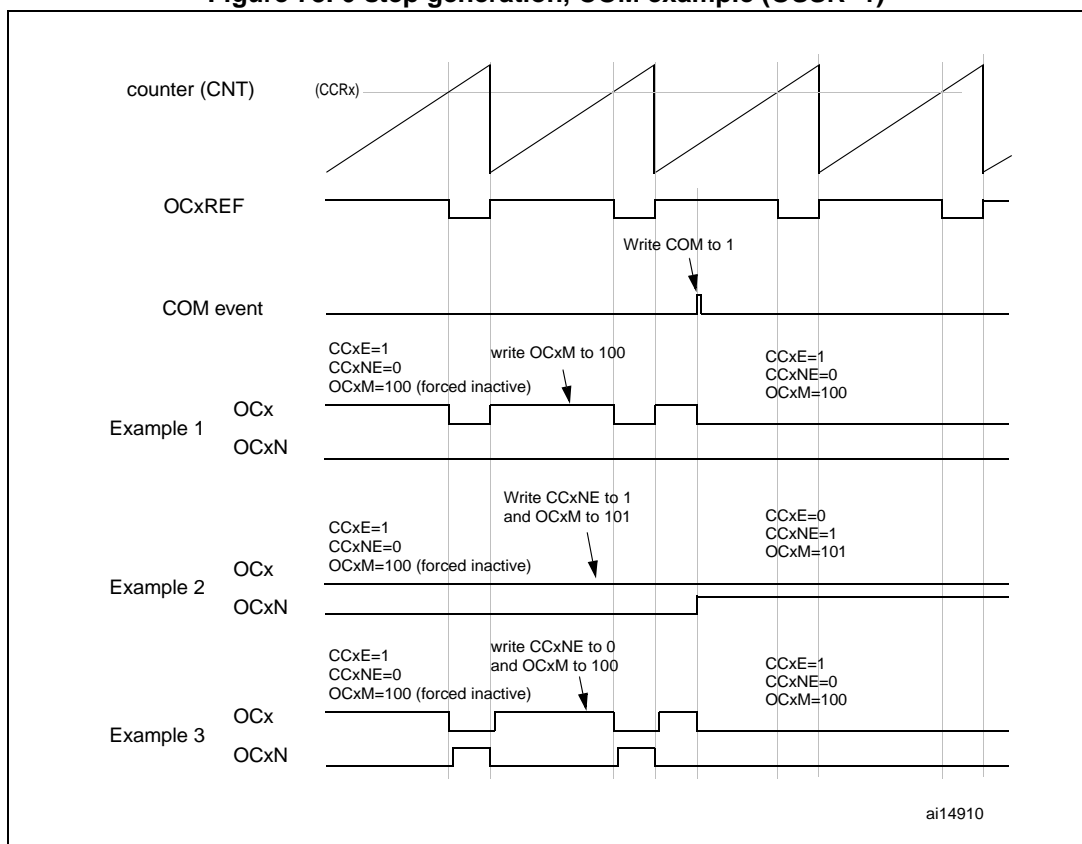
### 12.3.14 6-step PWM generation

When complementary outputs are used on a channel, preload bits are available on the OCxM, CCxE and CCxNE bits. The preload bits are transferred to the shadow bits at the COM commutation event. Thus you can program in advance the configuration for the next step and change the configuration of all the channels at the same time. COM can be generated by software by setting the COM bit in the TIMx\_EGR register or by hardware (on TRGI rising edge).

A flag is set when the COM event occurs (COMIF bit in the TIMx\_SR register), which can generate an interrupt (if the COMIE bit is set in the TIMx\_DIER register) or a DMA request (if the COMDE bit is set in the TIMx\_DIER register).

Figure 78 describes the behavior of the OCx and OCxN outputs when a COM event occurs, in 3 different examples of programmed configurations.

Figure 78. 6-step generation, COM example (OSSR=1)



### 12.3.15 One-pulse mode

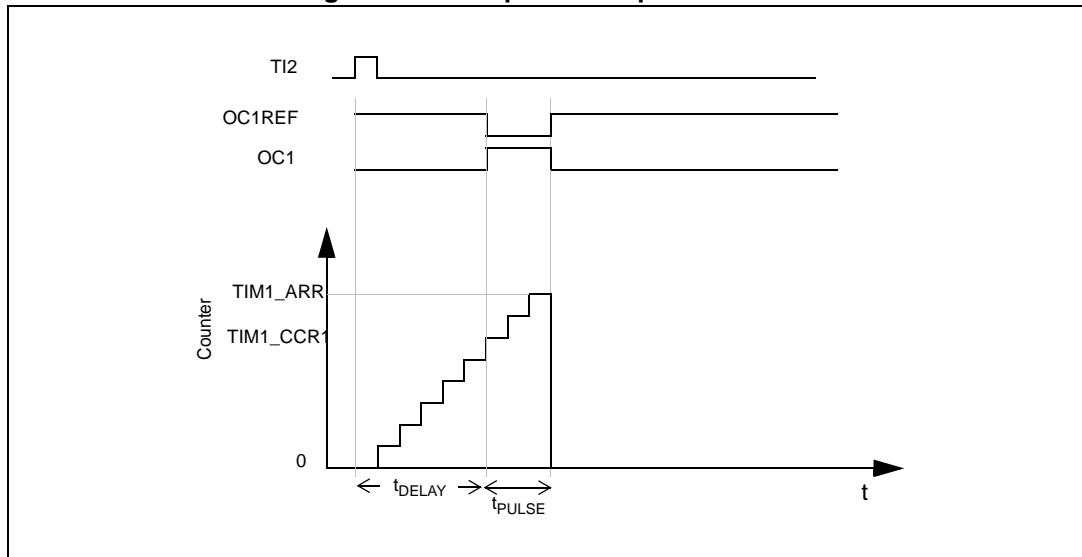
One-pulse mode (OPM) is a particular case of the previous modes. It allows the counter to be started in response to a stimulus and to generate a pulse with a programmable length after a programmable delay.

Starting the counter can be controlled through the slave mode controller. Generating the waveform can be done in output compare mode or PWM mode. You select One-pulse mode by setting the OPM bit in the TIMx\_CR1 register. This makes the counter stop automatically at the next update event UEV.

A pulse can be correctly generated only if the compare value is different from the counter initial value. Before starting (when the timer is waiting for the trigger), the configuration must be:

- In upcounting:  $CNT < CCRx \leq ARR$  (in particular,  $0 < CCRx$ )
- In downcounting:  $CNT > CCRx$

**Figure 79. Example of one pulse mode.**



For example you may want to generate a positive pulse on OC1 with a length of  $t_{PULSE}$  and after a delay of  $t_{DELAY}$  as soon as a positive edge is detected on the TI2 input pin.

Let's use TI2FP2 as trigger 1:

- Map TI2FP2 to TI2 by writing  $CC2S='01'$  in the TIMx\_CCMR1 register.
- TI2FP2 must detect a rising edge, write  $CC2P='0'$  and  $CC2NP='0'$  in the TIMx\_CCER register.
- Configure TI2FP2 as trigger for the slave mode controller (TRGI) by writing  $TS='110'$  in the TIMx\_SMCR register.
- TI2FP2 is used to start the counter by writing SMS to '110' in the TIMx\_SMCR register (trigger mode).

The OPM waveform is defined by writing the compare registers (taking into account the clock frequency and the counter prescaler).

- The  $t_{\text{DELAY}}$  is defined by the value written in the TIMx\_CCR1 register.
- The  $t_{\text{PULSE}}$  is defined by the difference between the auto-reload value and the compare value (TIMx\_ARR - TIMx\_CCR1).
- Let's say you want to build a waveform with a transition from '0' to '1' when a compare match occurs and a transition from '1' to '0' when the counter reaches the auto-reload value. To do this you enable PWM mode 2 by writing OC1M=111 in the TIMx\_CCMR1 register. You can optionally enable the preload registers by writing OC1PE='1' in the TIMx\_CCMR1 register and ARPE in the TIMx\_CR1 register. In this case you have to write the compare value in the TIMx\_CCR1 register, the auto-reload value in the TIMx\_ARR register, generate an update by setting the UG bit and wait for external trigger event on TI2. CC1P is written to '0' in this example.

In our example, the DIR and CMS bits in the TIMx\_CR1 register should be low.

You only want 1 pulse (Single mode), so you write '1' in the OPM bit in the TIMx\_CR1 register to stop the counter at the next update event (when the counter rolls over from the auto-reload value back to 0). When OPM bit in the TIMx\_CR1 register is set to '0', so the Repetitive Mode is selected.

Particular case: OCx fast enable:

In One-pulse mode, the edge detection on Tlx input set the CEN bit which enables the counter. Then the comparison between the counter and the compare value makes the output toggle. But several clock cycles are needed for these operations and it limits the minimum delay  $t_{\text{DELAY min}}$  we can get.

If you want to output a waveform with the minimum delay, you can set the OCxFE bit in the TIMx\_CCMRx register. Then OCxRef (and OCx) are forced in response to the stimulus, without taking in account the comparison. Its new level is the same as if a compare match had occurred. OCxFE acts only if the channel is configured in PWM1 or PWM2 mode.

### 12.3.16 Encoder interface mode

To select Encoder Interface mode write SMS='001' in the TIMx\_SMCR register if the counter is counting on TI2 edges only, SMS='010' if it is counting on TI1 edges only and SMS='011' if it is counting on both TI1 and TI2 edges.

Select the TI1 and TI2 polarity by programming the CC1P and CC2P bits in the TIMx\_CCER register. When needed, you can program the input filter as well. CC1NP and CC2NP must be kept low.

The two inputs TI1 and TI2 are used to interface to an incremental encoder. Refer to [Table 49](#). The counter is clocked by each valid transition on TI1FP1 or TI2FP2 (TI1 and TI2 after input filter and polarity selection, TI1FP1=TI1 if not filtered and not inverted, TI2FP2=TI2 if not filtered and not inverted) assuming that it is enabled (CEN bit in TIMx\_CR1 register written to '1'). The sequence of transitions of the two inputs is evaluated and generates count pulses as well as the direction signal. Depending on the sequence the counter counts up or down, the DIR bit in the TIMx\_CR1 register is modified by hardware accordingly. The DIR bit is calculated at each transition on any input (TI1 or TI2), whatever the counter is counting on TI1 only, TI2 only or both TI1 and TI2.

Encoder interface mode acts simply as an external clock with direction selection. This means that the counter just counts continuously between 0 and the auto-reload value in the TIMx\_ARR register (0 to ARR or ARR down to 0 depending on the direction). So you must

configure TIMx\_ARR before starting. in the same way, the capture, compare, prescaler, repetition counter, trigger output features continue to work as normal. Encoder mode and External clock mode 2 are not compatible and must not be selected together.

In this mode, the counter is modified automatically following the speed and the direction of the incremental encoder and its content, therefore, always represents the encoder's position. The count direction correspond to the rotation direction of the connected sensor. The table summarizes the possible combinations, assuming T11 and T12 don't switch at the same time.

**Table 49. Counting direction versus encoder signals**

Active edge	Level on opposite signal (TI1FP1 for TI2, TI2FP2 for TI1)	TI1FP1 signal		TI2FP2 signal	
		Rising	Falling	Rising	Falling
Counting on T11 only	High	Down	Up	No Count	No Count
	Low	Up	Down	No Count	No Count
Counting on T12 only	High	No Count	No Count	Up	Down
	Low	No Count	No Count	Down	Up
Counting on T11 and T12	High	Down	Up	Up	Down
	Low	Up	Down	Down	Up

An external incremental encoder can be connected directly to the MCU without external interface logic. However, comparators are normally be used to convert the encoder's differential outputs to digital signals. This greatly increases noise immunity. The third encoder output which indicate the mechanical zero position, may be connected to an external interrupt input and trigger a counter reset.

Figure 80 gives an example of counter operation, showing count signal generation and direction control. It also shows how input jitter is compensated where both edges are selected. This might occur if the sensor is positioned near to one of the switching points. For this example we assume that the configuration is the following:

- CC1S='01' (TIMx\_CCMR1 register, TI1FP1 mapped on T11).
- CC2S='01' (TIMx\_CCMR2 register, TI1FP2 mapped on T12).
- CC1P='0', CC1NP='0', and IC1F = '0000' (TIMx\_CCER register, TI1FP1 non-inverted, TI1FP1=TI1).
- CC2P='0', CC2NP='0', and IC2F = '0000' (TIMx\_CCER register, TI1FP2 non-inverted, TI1FP2= TI2).
- SMS='011' (TIMx\_SMCR register, both inputs are active on both rising and falling edges).
- CEN='1' (TIMx\_CR1 register, Counter enabled).



**Figure 80. Example of counter operation in encoder interface mode.**

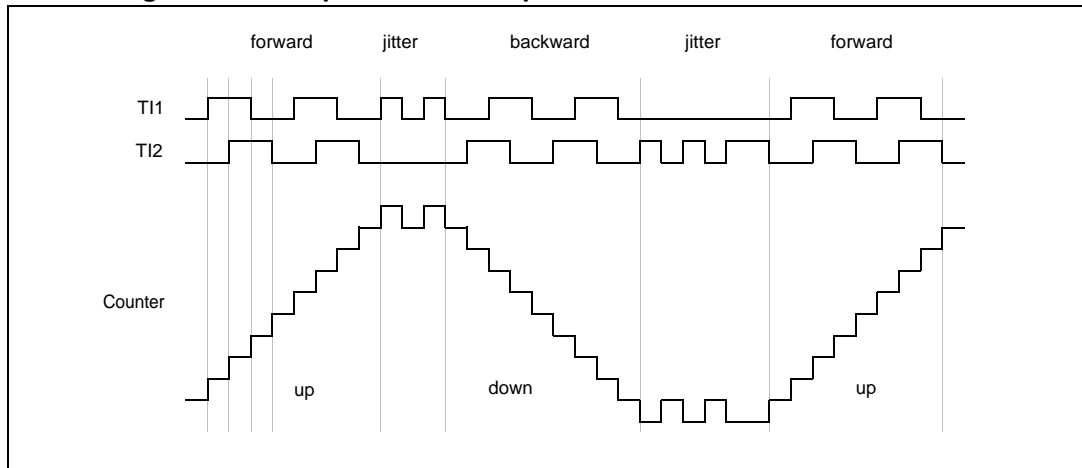
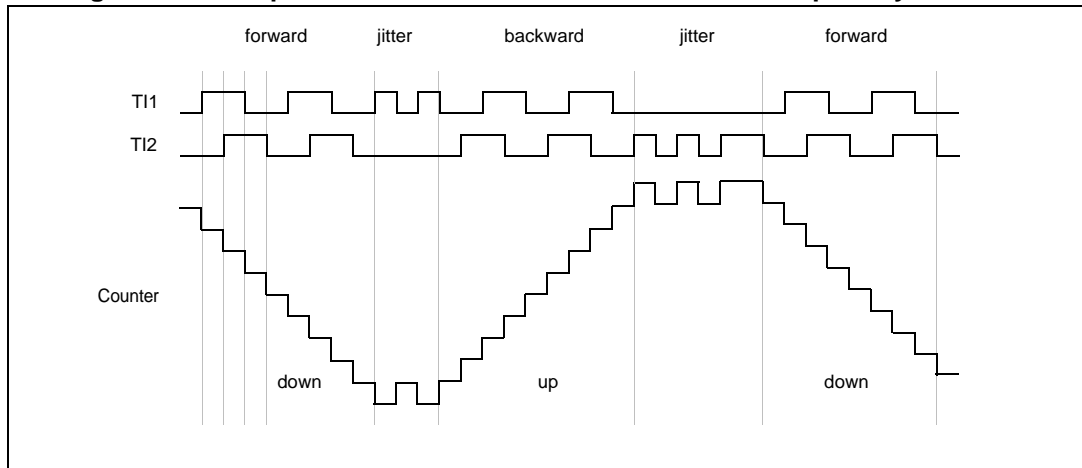


Figure 81 gives an example of counter behavior when TI1FP1 polarity is inverted (same configuration as above except CC1P='1').

**Figure 81. Example of encoder interface mode with TI1FP1 polarity inverted.**



The timer, when configured in Encoder Interface mode provides information on the sensor's current position. You can obtain dynamic information (speed, acceleration, deceleration) by measuring the period between two encoder events using a second timer configured in capture mode. The output of the encoder which indicates the mechanical zero can be used for this purpose. Depending on the time between two events, the counter can also be read at regular times. You can do this by latching the counter value into a third input capture register if available (then the capture signal must be periodic and can be generated by another timer). when available, it is also possible to read its value through a DMA request generated by a real-time clock.

### 12.3.17 Timer input XOR function

The TI1S bit in the TIMx\_CR2 register, allows the input filter of channel 1 to be connected to the output of a XOR gate, combining the three input pins TIMx\_CH1, TIMx\_CH2 and TIMx\_CH3.

The XOR output can be used with all the timer input functions such as trigger or input capture. An example of this feature used to interface Hall sensors is given in

[Section 12.3.18](#) below.

### 12.3.18 Interfacing with Hall sensors

This is done using the advanced-control timers (TIM1) to generate PWM signals to drive the motor and another timer TIMx (TIM2, TIM3, TIM4 or TIM5) referred to as “interfacing timer” in [Figure 82](#). The “interfacing timer” captures the 3 timer input pins (TIMx\_CH1, TIMx\_CH2, and TIMx\_CH3) connected through a XOR to the TI1 input channel (selected by setting the TI1S bit in the TIMx\_CR2 register).

The slave mode controller is configured in reset mode; the slave input is TI1F\_ED. Thus, each time one of the 3 inputs toggles, the counter restarts counting from 0. This creates a time base triggered by any change on the Hall inputs.

On the “interfacing timer”, capture/compare channel 1 is configured in capture mode, capture signal is TRC (see [Figure 65: Capture/compare channel \(example: channel 1 input stage\) on page 258](#)). The captured value, which corresponds to the time elapsed between 2 changes on the inputs, gives information about motor speed.

The “interfacing timer” can be used in output mode to generate a pulse which changes the configuration of the channels of the advanced-control timer (TIM1) (by triggering a COM event). The TIM1 timer is used to generate PWM signals to drive the motor. To do this, the interfacing timer channel must be programmed so that a positive pulse is generated after a programmed delay (in output compare or PWM mode). This pulse is sent to the advanced-control timer (TIM1) through the TRGO output.

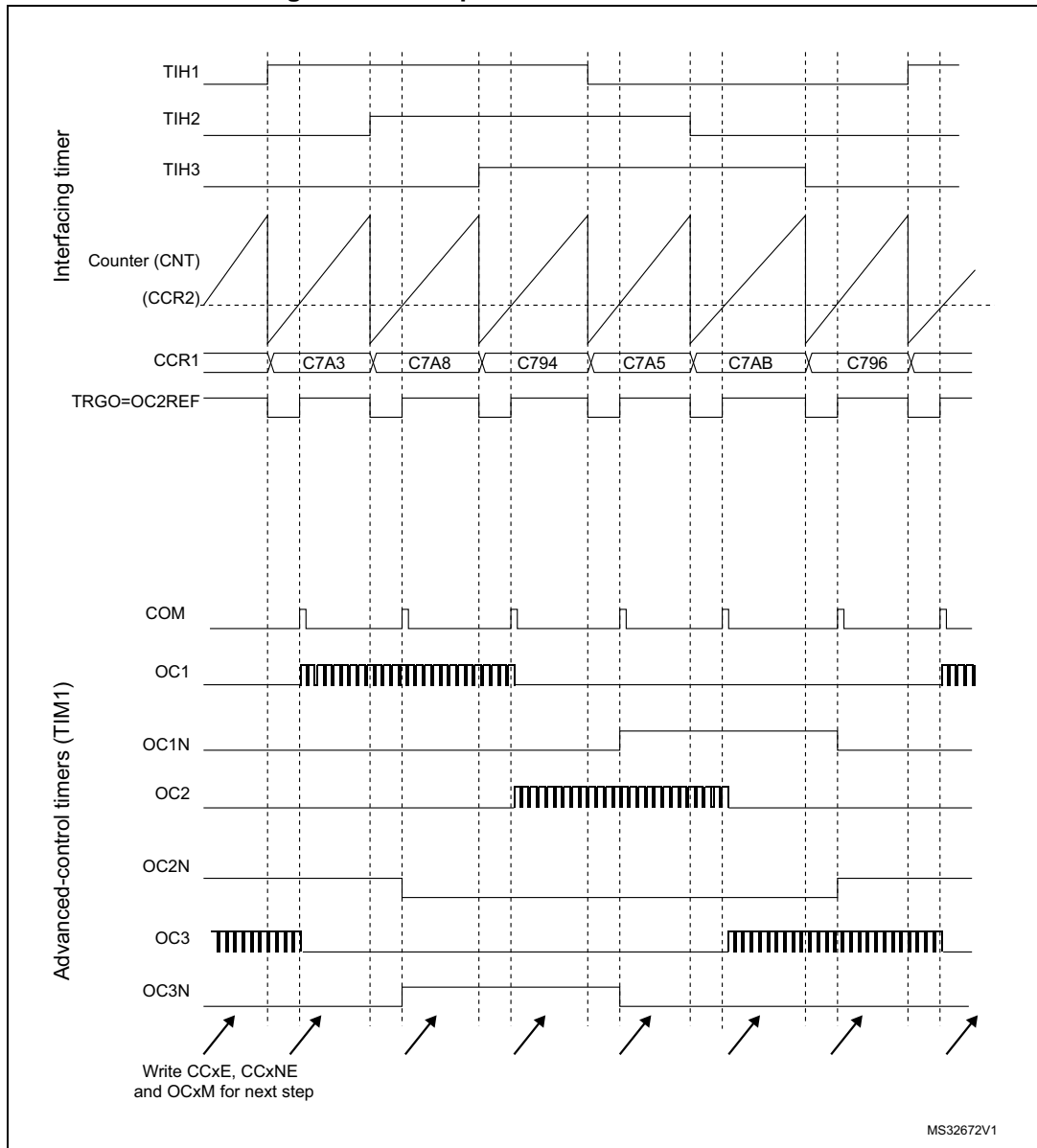
Example: you want to change the PWM configuration of your advanced-control timer TIM1 after a programmed delay each time a change occurs on the Hall inputs connected to one of the TIMx timers.

- Configure 3 timer inputs ORed to the TI1 input channel by writing the TI1S bit in the TIMx\_CR2 register to ‘1’,
- Program the time base: write the TIMx\_ARR to the max value (the counter must be cleared by the TI1 change. Set the prescaler to get a maximum counter period longer than the time between 2 changes on the sensors,
- Program channel 1 in capture mode (TRC selected): write the CC1S bits in the TIMx\_CCMR1 register to ‘11’. You can also program the digital filter if needed,
- Program channel 2 in PWM 2 mode with the desired delay: write the OC2M bits to ‘111’ and the CC2S bits to ‘00’ in the TIMx\_CCMR1 register,
- Select OC2REF as trigger output on TRGO: write the MMS bits in the TIMx\_CR2 register to ‘101’,

In the advanced-control timer TIM1, the right ITR input must be selected as trigger input, the timer is programmed to generate PWM signals, the capture/compare control signals are preloaded (CCPC=1 in the TIMx\_CR2 register) and the COM event is controlled by the trigger input (CCUS=1 in the TIMx\_CR2 register). The PWM control bits (CCxE, OCxM) are written after a COM event for the next step (this can be done in an interrupt subroutine generated by the rising edge of OC2REF).

[Figure 82](#) describes this example.

Figure 82. Example of hall sensor interface



MS32672V1

### 12.3.19 TIMx and external trigger synchronization

The TIMx timer can be synchronized with an external trigger in several modes: Reset mode, Gated mode and Trigger mode.

#### Slave mode: Reset mode

The counter and its prescaler can be reinitialized in response to an event on a trigger input. Moreover, if the URS bit from the TIMx\_CR1 register is low, an update event UEV is generated. Then all the preloaded registers (TIMx\_ARR, TIMx\_CCRx) are updated.

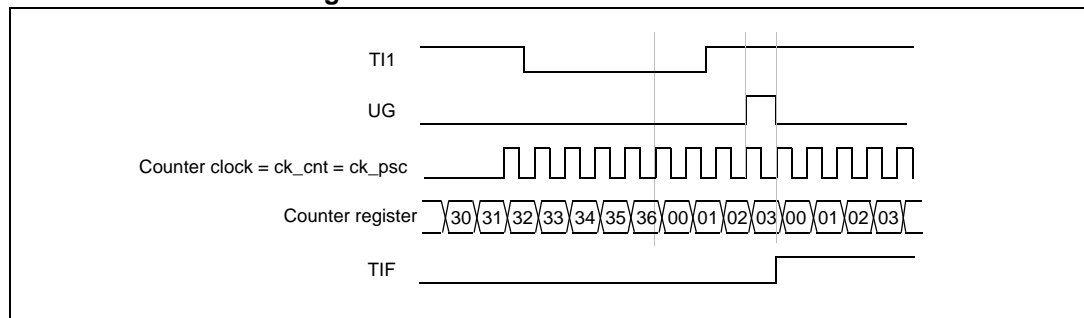
In the following example, the upcounter is cleared in response to a rising edge on TI1 input:

- Configure the channel 1 to detect rising edges on TI1. Configure the input filter duration (in this example, we don't need any filter, so we keep IC1F=0000). The capture prescaler is not used for triggering, so you don't need to configure it. The CC1S bits select the input capture source only, CC1S = 01 in the TIMx\_CCMR1 register. Write CC1P=0 and CC1NP='0' in TIMx\_CCER register to validate the polarity (and detect rising edges only).
- Configure the timer in reset mode by writing SMS=100 in TIMx\_SMCR register. Select TI1 as the input source by writing TS=101 in TIMx\_SMCR register.
- Start the counter by writing CEN=1 in the TIMx\_CR1 register.

The counter starts counting on the internal clock, then behaves normally until TI1 rising edge. When TI1 rises, the counter is cleared and restarts from 0. In the meantime, the trigger flag is set (TIF bit in the TIMx\_SR register) and an interrupt request, or a DMA request can be sent if enabled (depending on the TIE and TDE bits in TIMx\_DIER register).

The following figure shows this behavior when the auto-reload register TIMx\_ARR=0x36. The delay between the rising edge on TI1 and the actual reset of the counter is due to the resynchronization circuit on TI1 input.

**Figure 83. Control circuit in reset mode**



**Slave mode: Gated mode**

The counter can be enabled depending on the level of a selected input.

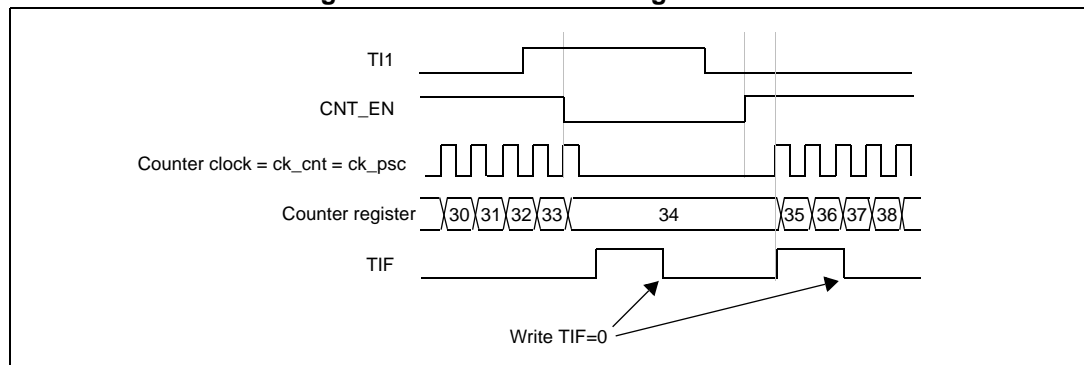
In the following example, the upcounter counts only when TI1 input is low:

- Configure the channel 1 to detect low levels on TI1. Configure the input filter duration (in this example, we don't need any filter, so we keep IC1F=0000). The capture prescaler is not used for triggering, so you don't need to configure it. The CC1S bits select the input capture source only, CC1S=01 in TIMx\_CCMR1 register. Write CC1P=1 and CC1NP='0' in TIMx\_CCER register to validate the polarity (and detect low level only).
- Configure the timer in gated mode by writing SMS=101 in TIMx\_SMCR register. Select TI1 as the input source by writing TS=101 in TIMx\_SMCR register.
- Enable the counter by writing CEN=1 in the TIMx\_CR1 register (in gated mode, the counter doesn't start if CEN=0, whatever is the trigger input level).

The counter starts counting on the internal clock as long as TI1 is low and stops as soon as TI1 becomes high. The TIF flag in the TIMx\_SR register is set both when the counter starts or stops.

The delay between the rising edge on TI1 and the actual stop of the counter is due to the resynchronization circuit on TI1 input.

**Figure 84. Control circuit in gated mode**



**Slave mode: Trigger mode**

The counter can start in response to an event on a selected input.

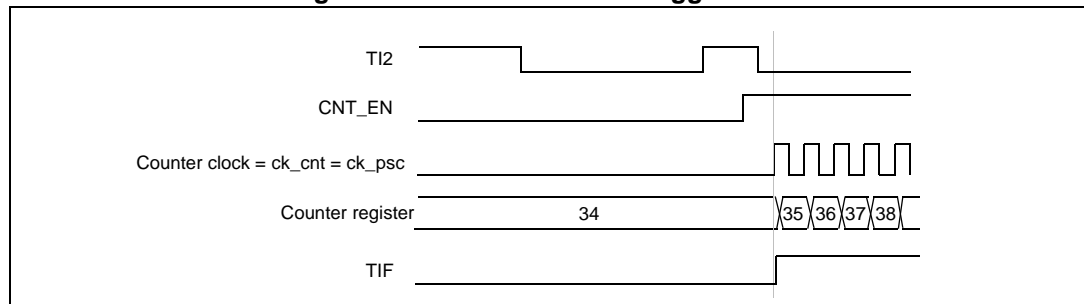
In the following example, the upcounter starts in response to a rising edge on TI2 input:

- Configure the channel 2 to detect rising edges on TI2. Configure the input filter duration (in this example, we don't need any filter, so we keep IC2F=0000). The capture prescaler is not used for triggering, so you don't need to configure it. The CC2S bits are configured to select the input capture source only, CC2S=01 in TIMx\_CCMR1 register. Write CC2P=1 and CC2NP=0 in TIMx\_CCER register to validate the polarity (and detect low level only).
- Configure the timer in trigger mode by writing SMS=110 in TIMx\_SMCR register. Select TI2 as the input source by writing TS=110 in TIMx\_SMCR register.

When a rising edge occurs on TI2, the counter starts counting on the internal clock and the TIF flag is set.

The delay between the rising edge on TI2 and the actual start of the counter is due to the resynchronization circuit on TI2 input.

**Figure 85. Control circuit in trigger mode**



**Slave mode: external clock mode 2 + trigger mode**

The external clock mode 2 can be used in addition to another slave mode (except external clock mode 1 and encoder mode). In this case, the ETR signal is used as external clock input, and another input can be selected as trigger input (in reset mode, gated mode or trigger mode). It is recommended not to select ETR as TRGI through the TS bits of TIMx\_SMCR register.

In the following example, the upcounter is incremented at each rising edge of the ETR signal as soon as a rising edge of TI1 occurs:

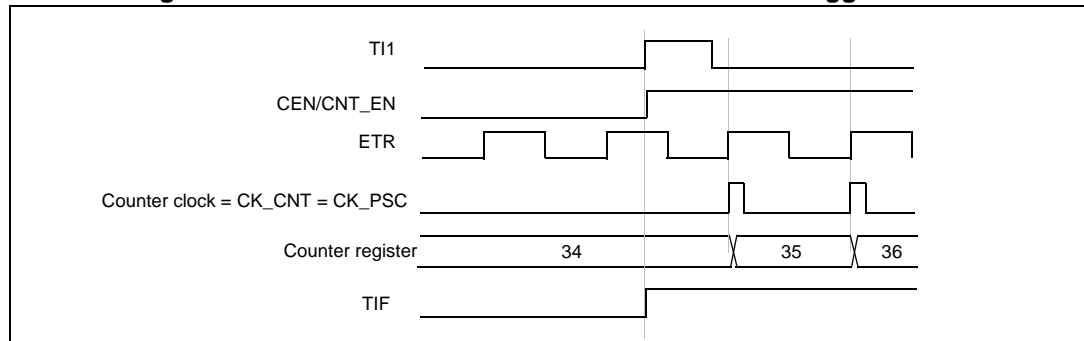
1. Configure the external trigger input circuit by programming the TIMx\_SMCR register as follows:
  - ETF = 0000: no filter
  - ETPS = 00: prescaler disabled
  - ETP = 0: detection of rising edges on ETR and ECE=1 to enable the external clock mode 2.
2. Configure the channel 1 as follows, to detect rising edges on TI1:
  - IC1F=0000: no filter.
  - The capture prescaler is not used for triggering and does not need to be configured.
  - CC1S=01 in TIMx\_CCMR1 register to select only the input capture source

- CC1P=0 and CC1NP='0' in TIMx\_CCER register to validate the polarity (and detect rising edge only).
3. Configure the timer in trigger mode by writing SMS=110 in TIMx\_SMCR register. Select TI1 as the input source by writing TS=101 in TIMx\_SMCR register.

A rising edge on TI1 enables the counter and sets the TIF flag. The counter then counts on ETR rising edges.

The delay between the rising edge of the ETR signal and the actual reset of the counter is due to the resynchronization circuit on ETRP input.

**Figure 86. Control circuit in external clock mode 2 + trigger mode**



### 12.3.20 Timer synchronization

The TIM timers are linked together internally for timer synchronization or chaining. Refer to [Section 13.3.15: Timer synchronization on page 341](#) for details.

### 12.3.21 Debug mode

When the microcontroller enters debug mode (Cortex<sup>®</sup>-M4 with FPU core halted), the TIMx counter either continues to work normally or stops, depending on DBG\_TIMx\_STOP configuration bit in DBG module. For more details, refer to [Section 23.16.2: Debug support for timers, watchdog and I2C](#).

## 12.4 TIM1 registers

Refer to [Section 1.1 on page 34](#) for a list of abbreviations used in register descriptions.

The peripheral registers must be written by half-words (16 bits) or words (32 bits). Read accesses can be done by bytes (8 bits), half-word (16 bits) or words (32 bits).

### 12.4.1 TIM1 control register 1 (TIMx\_CR1)

Address offset: 0x00

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved						CKD[1:0]		ARPE	CMS[1:0]		DIR	OPM	URS	UDIS	CEN
						rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 15:10 Reserved, must be kept at reset value.

Bits 9:8 **CKD[1:0]**: Clock division

This bit-field indicates the division ratio between the timer clock (CK\_INT) frequency and the dead-time and sampling clock ( $t_{DTS}$ ) used by the dead-time generators and the digital filters (ETR, TIX),

00:  $t_{DTS}=t_{CK\_INT}$

01:  $t_{DTS}=2*t_{CK\_INT}$

10:  $t_{DTS}=4*t_{CK\_INT}$

11: Reserved, do not program this value

Bit 7 **ARPE**: Auto-reload preload enable

0: TIMx\_ARR register is not buffered

1: TIMx\_ARR register is buffered

Bits 6:5 **CMS[1:0]**: Center-aligned mode selection

00: Edge-aligned mode. The counter counts up or down depending on the direction bit (DIR).

01: Center-aligned mode 1. The counter counts up and down alternatively. Output compare interrupt flags of channels configured in output (CCxS=00 in TIMx\_CCMRx register) are set only when the counter is counting down.

10: Center-aligned mode 2. The counter counts up and down alternatively. Output compare interrupt flags of channels configured in output (CCxS=00 in TIMx\_CCMRx register) are set only when the counter is counting up.

11: Center-aligned mode 3. The counter counts up and down alternatively. Output compare interrupt flags of channels configured in output (CCxS=00 in TIMx\_CCMRx register) are set both when the counter is counting up or down.

*Note: It is not allowed to switch from edge-aligned mode to center-aligned mode as long as the counter is enabled (CEN=1)*

Bit 4 **DIR**: Direction

0: Counter used as upcounter

1: Counter used as downcounter

*Note: This bit is read only when the timer is configured in Center-aligned mode or Encoder mode.*

Bit 3 **OPM**: One pulse mode

0: Counter is not stopped at update event

1: Counter stops counting at the next update event (clearing the bit CEN)



Bit 2 **URS**: Update request source

This bit is set and cleared by software to select the UEV event sources.

0: Any of the following events generate an update interrupt or DMA request if enabled.

These events can be:

- Counter overflow/underflow
- Setting the UG bit
- Update generation through the slave mode controller

1: Only counter overflow/underflow generates an update interrupt or DMA request if enabled.

Bit 1 **UDIS**: Update disable

This bit is set and cleared by software to enable/disable UEV event generation.

0: UEV enabled. The Update (UEV) event is generated by one of the following events:

- Counter overflow/underflow
- Setting the UG bit
- Update generation through the slave mode controller

Buffered registers are then loaded with their preload values.

1: UEV disabled. The Update event is not generated, shadow registers keep their value (ARR, PSC, CCRx). However the counter and the prescaler are reinitialized if the UG bit is set or if a hardware reset is received from the slave mode controller.

Bit 0 **CEN**: Counter enable

0: Counter disabled

1: Counter enabled

*Note: External clock, gated mode and encoder mode can work only if the CEN bit has been previously set by software. However trigger mode can set the CEN bit automatically by hardware.*

### 12.4.2 TIM1 control register 2 (TIMx\_CR2)

Address offset: 0x04

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Res.	OIS4	OIS3N	OIS3	OIS2N	OIS2	OIS1N	OIS1	TI1S	MMS[2:0]			CCDS	CCUS	Res.	CCPC
	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw		rw

Bit 15 Reserved, must be kept at reset value.

Bit 14 **OIS4**: Output Idle state 4 (OC4 output)  
refer to OIS1 bit

Bit 13 **OIS3N**: Output Idle state 3 (OC3N output)  
refer to OIS1N bit

Bit 12 **OIS3**: Output Idle state 3 (OC3 output)  
refer to OIS1 bit

Bit 11 **OIS2N**: Output Idle state 2 (OC2N output)  
refer to OIS1N bit

Bit 10 **OIS2**: Output Idle state 2 (OC2 output)  
refer to OIS1 bit

Bit 9 **OIS1N**: Output Idle state 1 (OC1N output)

0: OC1N=0 after a dead-time when MOE=0

1: OC1N=1 after a dead-time when MOE=0

*Note: This bit can not be modified as long as LOCK level 1, 2 or 3 has been programmed (LOCK bits in TIMx\_BDTR register).*

Bit 8 **OIS1**: Output Idle state 1 (OC1 output)

0: OC1=0 (after a dead-time if OC1N is implemented) when MOE=0

1: OC1=1 (after a dead-time if OC1N is implemented) when MOE=0

*Note: This bit can not be modified as long as LOCK level 1, 2 or 3 has been programmed (LOCK bits in TIMx\_BDTR register).*

Bit 7 **TI1S**: TI1 selection

0: The TIMx\_CH1 pin is connected to TI1 input

1: The TIMx\_CH1, CH2 and CH3 pins are connected to the TI1 input (XOR combination)

Bits 6:4 **MMS[2:0]**: Master mode selection

These bits allow to select the information to be sent in master mode to slave timers for synchronization (TRGO). The combination is as follows:

000: **Reset** - the UG bit from the TIMx\_EGR register is used as trigger output (TRGO). If the reset is generated by the trigger input (slave mode controller configured in reset mode) then the signal on TRGO is delayed compared to the actual reset.

001: **Enable** - the Counter Enable signal CNT\_EN is used as trigger output (TRGO). It is useful to start several timers at the same time or to control a window in which a slave timer is enable. The Counter Enable signal is generated by a logic OR between CEN control bit and the trigger input when configured in gated mode. When the Counter Enable signal is controlled by the trigger input, there is a delay on TRGO, except if the master/slave mode is selected (see the MSM bit description in TIMx\_SMCR register).

010: **Update** - The update event is selected as trigger output (TRGO). For instance a master timer can then be used as a prescaler for a slave timer.

011: **Compare Pulse** - The trigger output send a positive pulse when the CC1IF flag is to be set (even if it was already high), as soon as a capture or a compare match occurred. (TRGO).

100: **Compare** - OC1REF signal is used as trigger output (TRGO)

101: **Compare** - OC2REF signal is used as trigger output (TRGO)

110: **Compare** - OC3REF signal is used as trigger output (TRGO)

111: **Compare** - OC4REF signal is used as trigger output (TRGO)

*Note: The clock of the slave timer and ADC must be enabled prior to receiving events from the master timer, and must not be changed on-the-fly while triggers are received from the master timer.*

Bit 3 **CCDS**: Capture/compare DMA selection

0: CCx DMA request sent when CCx event occurs

1: CCx DMA requests sent when update event occurs

Bit 2 **CCUS**: Capture/compare control update selection

0: When capture/compare control bits are preloaded (CCPC=1), they are updated by setting the COMG bit only

1: When capture/compare control bits are preloaded (CCPC=1), they are updated by setting the COMG bit or when an rising edge occurs on TRGI

*Note: This bit acts only on channels that have a complementary output.*

Bit 1 Reserved, must be kept at reset value.

Bit 0 **CCPC**: Capture/compare preloaded control

0: CCxE, CCxNE and OCxM bits are not preloaded

1: CCxE, CCxNE and OCxM bits are preloaded, after having been written, they are updated only when a commutation event (COM) occurs (COMG bit set or rising edge detected on TRGI, depending on the CCUS bit).

*Note: This bit acts only on channels that have a complementary output.*

### 12.4.3 TIM1 slave mode control register (TIMx\_SMCR)

Address offset: 0x08

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
ETP	ECE	ETPS[1:0]		ETF[3:0]				MSM	TS[2:0]			Res.	SMS[2:0]		
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	Res.	rw	rw	rw

Bit 15 **ETP**: External trigger polarity

This bit selects whether ETR or  $\overline{ETR}$  is used for trigger operations

0: ETR is non-inverted, active at high level or rising edge.

1: ETR is inverted, active at low level or falling edge.

Bit 14 **ECE**: External clock enable

This bit enables External clock mode 2.

0: External clock mode 2 disabled

1: External clock mode 2 enabled. The counter is clocked by any active edge on the ETRF signal.

*Note:* **1:** Setting the ECE bit has the same effect as selecting external clock mode 1 with TRGI connected to ETRF (SMS=111 and TS=111).

**2:** It is possible to simultaneously use external clock mode 2 with the following slave modes: reset mode, gated mode and trigger mode. Nevertheless, TRGI must not be connected to ETRF in this case (TS bits must not be 111).

**3:** If external clock mode 1 and external clock mode 2 are enabled at the same time, the external clock input is ETRF.

Bits 13:12 **ETPS[1:0]**: External trigger prescaler

External trigger signal ETRP frequency must be at most 1/4 of TIMxCLK frequency. A prescaler can be enabled to reduce ETRP frequency. It is useful when inputting fast external clocks.

00: Prescaler OFF

01: ETRP frequency divided by 2

10: ETRP frequency divided by 4

11: ETRP frequency divided by 8

Bits 11:8 **ETF[3:0]**: External trigger filter

This bit-field then defines the frequency used to sample ETRP signal and the length of the digital filter applied to ETRP. The digital filter is made of an event counter in which N events are needed to validate a transition on the output:

0000: No filter, sampling is done at  $f_{DTS}$

0001:  $f_{SAMPLING}=f_{CK\_INT}$ , N=2

0010:  $f_{SAMPLING}=f_{CK\_INT}$ , N=4

0011:  $f_{SAMPLING}=f_{CK\_INT}$ , N=8

0100:  $f_{SAMPLING}=f_{DTS}/2$ , N=6

0101:  $f_{SAMPLING}=f_{DTS}/2$ , N=8

0110:  $f_{SAMPLING}=f_{DTS}/4$ , N=6

0111:  $f_{SAMPLING}=f_{DTS}/4$ , N=8

1000:  $f_{SAMPLING}=f_{DTS}/8$ , N=6

1001:  $f_{SAMPLING}=f_{DTS}/8$ , N=8

1010:  $f_{SAMPLING}=f_{DTS}/16$ , N=5

1011:  $f_{SAMPLING}=f_{DTS}/16$ , N=6

1100:  $f_{SAMPLING}=f_{DTS}/16$ , N=8

1101:  $f_{SAMPLING}=f_{DTS}/32$ , N=5

1110:  $f_{SAMPLING}=f_{DTS}/32$ , N=6

1111:  $f_{SAMPLING}=f_{DTS}/32$ , N=8

Bit 7 **MSM**: Master/slave mode

0: No action

1: The effect of an event on the trigger input (TRGI) is delayed to allow a perfect synchronization between the current timer and its slaves (through TRGO). It is useful if we want to synchronize several timers on a single external event.

Bits 6:4 **TS[2:0]**: Trigger selection

This bit-field selects the trigger input to be used to synchronize the counter.

000: Internal Trigger 0 (ITR0)

001: Internal Trigger 1 (ITR1)

010: Internal Trigger 2 (ITR2)

011: Internal Trigger 3 (ITR3)

100: T11 Edge Detector (TI1F\_ED)

101: Filtered Timer Input 1 (TI1FP1)

110: Filtered Timer Input 2 (TI2FP2)

111: External Trigger input (ETRF)

See [Table 50: TIMx Internal trigger connection on page 289](#) for more details on ITRx meaning for each Timer.

*Note: These bits must be changed only when they are not used (e.g. when SMS=000) to avoid wrong edge detections at the transition.*

## Bit 3 Reserved, must be kept at reset value.

Bits 2:0 **SMS**: Slave mode selection

When external signals are selected the active edge of the trigger signal (TRGI) is linked to the polarity selected on the external input (see Input Control register and Control Register description).

000: Slave mode disabled - if CEN = '1' then the prescaler is clocked directly by the internal clock.

001: Encoder mode 1 - Counter counts up/down on TI2FP1 edge depending on TI1FP2 level.

010: Encoder mode 2 - Counter counts up/down on TI1FP2 edge depending on TI2FP1 level.

011: Encoder mode 3 - Counter counts up/down on both TI1FP1 and TI2FP2 edges depending on the level of the other input.

100: Reset Mode - Rising edge of the selected trigger input (TRGI) reinitializes the counter and generates an update of the registers.

101: Gated Mode - The counter clock is enabled when the trigger input (TRGI) is high. The counter stops (but is not reset) as soon as the trigger becomes low. Both start and stop of the counter are controlled.

110: Trigger Mode - The counter starts at a rising edge of the trigger TRGI (but it is not reset). Only the start of the counter is controlled.

111: External Clock Mode 1 - Rising edges of the selected trigger (TRGI) clock the counter.

*Note: The gated mode must not be used if TI1F\_ED is selected as the trigger input (TS='100'). Indeed, TI1F\_ED outputs 1 pulse for each transition on TI1F, whereas the gated mode checks the level of the trigger signal.*

*The clock of the slave timer must be enabled prior to receiving events from the master timer, and must not be changed on-the-fly while triggers are received from the master timer.*

**Table 50. TIMx Internal trigger connection**

Slave TIM	ITR0 (TS = 000)	ITR1 (TS = 001)	ITR2 (TS = 010)	ITR3 (TS = 011)
TIM1	TIM5_TRGO	TIM2_TRGO	TIM3_TRGO	TIM4_TRGO

**12.4.4 TIM1 DMA/interrupt enable register (TIMx\_DIER)**

Address offset: 0x0C

Reset value: 0x0000

	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Res.	TDE	COMDE	CC4DE	CC3DE	CC2DE	CC1DE	UDE	BIE	TIE	COMIE	CC4IE	CC3IE	CC2IE	CC1IE	UIE	
	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w

Bit 15 Reserved, must be kept at reset value.

Bit 14 **TDE**: Trigger DMA request enable  
 0: Trigger DMA request disabled  
 1: Trigger DMA request enabled

Bit 13 **COMDE**: COM DMA request enable  
 0: COM DMA request disabled  
 1: COM DMA request enabled



- Bit 12 **CC4DE**: Capture/Compare 4 DMA request enable  
0: CC4 DMA request disabled  
1: CC4 DMA request enabled
- Bit 11 **CC3DE**: Capture/Compare 3 DMA request enable  
0: CC3 DMA request disabled  
1: CC3 DMA request enabled
- Bit 10 **CC2DE**: Capture/Compare 2 DMA request enable  
0: CC2 DMA request disabled  
1: CC2 DMA request enabled
- Bit 9 **CC1DE**: Capture/Compare 1 DMA request enable  
0: CC1 DMA request disabled  
1: CC1 DMA request enabled
- Bit 8 **UDE**: Update DMA request enable  
0: Update DMA request disabled  
1: Update DMA request enabled
- Bit 7 **BIE**: Break interrupt enable  
0: Break interrupt disabled  
1: Break interrupt enabled
- Bit 6 **TIE**: Trigger interrupt enable  
0: Trigger interrupt disabled  
1: Trigger interrupt enabled
- Bit 5 **COMIE**: COM interrupt enable  
0: COM interrupt disabled  
1: COM interrupt enabled
- Bit 4 **CC4IE**: Capture/Compare 4 interrupt enable  
0: CC4 interrupt disabled  
1: CC4 interrupt enabled
- Bit 3 **CC3IE**: Capture/Compare 3 interrupt enable  
0: CC3 interrupt disabled  
1: CC3 interrupt enabled
- Bit 2 **CC2IE**: Capture/Compare 2 interrupt enable  
0: CC2 interrupt disabled  
1: CC2 interrupt enabled
- Bit 1 **CC1IE**: Capture/Compare 1 interrupt enable  
0: CC1 interrupt disabled  
1: CC1 interrupt enabled
- Bit 0 **UIE**: Update interrupt enable  
0: Update interrupt disabled  
1: Update interrupt enabled

### 12.4.5 TIM1 status register (TIMx\_SR)

Address offset: 0x10

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved		CC4OF	CC3OF	CC2OF	CC1OF	Res.	BIF	TIF	COMIF	CC4IF	CC3IF	CC2IF	CC1IF	UIF	
		rc_w0	rc_w0	rc_w0	rc_w0	Res.	rc_w0	rc_w0	rc_w0	rc_w0	rc_w0	rc_w0	rc_w0	rc_w0	

Bits 15:13 Reserved, must be kept at reset value.

Bit 12 **CC4OF**: Capture/Compare 4 overcapture flag  
refer to CC1OF description

Bit 11 **CC3OF**: Capture/Compare 3 overcapture flag  
refer to CC1OF description

Bit 10 **CC2OF**: Capture/Compare 2 overcapture flag  
refer to CC1OF description

Bit 9 **CC1OF**: Capture/Compare 1 overcapture flag  
This flag is set by hardware only when the corresponding channel is configured in input capture mode. It is cleared by software by writing it to '0'.  
0: No overcapture has been detected.  
1: The counter value has been captured in TIMx\_CCR1 register while CC1IF flag was already set

Bit 8 Reserved, must be kept at reset value.

Bit 7 **BIF**: Break interrupt flag  
This flag is set by hardware as soon as the break input goes active. It can be cleared by software if the break input is not active.  
0: No break event occurred.  
1: An active level has been detected on the break input.

Bit 6 **TIF**: Trigger interrupt flag  
This flag is set by hardware on trigger event (active edge detected on TRGI input when the slave mode controller is enabled in all modes but gated mode. It is set when the counter starts or stops when gated mode is selected. It is cleared by software.  
0: No trigger event occurred.  
1: Trigger interrupt pending.

Bit 5 **COMIF**: COM interrupt flag  
This flag is set by hardware on COM event (when Capture/compare Control bits - CCxE, CCxNE, OCxM - have been updated). It is cleared by software.  
0: No COM event occurred.  
1: COM interrupt pending.

Bit 4 **CC4IF**: Capture/Compare 4 interrupt flag  
refer to CC1IF description

Bit 3 **CC3IF**: Capture/Compare 3 interrupt flag  
refer to CC1IF description



- Bit 2 **CC2IF**: Capture/Compare 2 interrupt flag  
refer to CC1IF description
- Bit 1 **CC1IF**: Capture/Compare 1 interrupt flag  
**If channel CC1 is configured as output:**  
 This flag is set by hardware when the counter matches the compare value, with some exception in center-aligned mode (refer to the CMS bits in the TIMx\_CR1 register description). It is cleared by software.  
 0: No match.  
 1: The content of the counter TIMx\_CNT matches the content of the TIMx\_CCR1 register. When the contents of TIMx\_CCR1 are greater than the contents of TIMx\_ARR, the CC1IF bit goes high on the counter overflow (in upcounting and up/down-counting modes) or underflow (in downcounting mode)  
**If channel CC1 is configured as input:**  
 This bit is set by hardware on a capture. It is cleared by software or by reading the TIMx\_CCR1 register.  
 0: No input capture occurred  
 1: The counter value has been captured in TIMx\_CCR1 register (An edge has been detected on IC1 which matches the selected polarity)
- Bit 0 **UIF**: Update interrupt flag  
 This bit is set by hardware on an update event. It is cleared by software.  
 0: No update occurred.  
 1: Update interrupt pending. This bit is set by hardware when the registers are updated:
  - At overflow or underflow regarding the repetition counter value (update if repetition counter = 0) and if the UDIS=0 in the TIMx\_CR1 register.
  - When CNT is reinitialized by software using the UG bit in TIMx\_EGR register, if URS=0 and UDIS=0 in the TIMx\_CR1 register.
  - When CNT is reinitialized by a trigger event (refer to [Section 12.4.3: TIM1 slave mode control register \(TIMx\\_SMCR\)](#)), if URS=0 and UDIS=0 in the TIMx\_CR1 register.

### 12.4.6 TIM1 event generation register (TIMx\_EGR)

Address offset: 0x14

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved								BG	TG	COMG	CC4G	CC3G	CC2G	CC1G	UG
								w	w	w	w	w	w	w	w

Bits 15:8 Reserved, must be kept at reset value.

- Bit 7 **BG**: Break generation  
 This bit is set by software in order to generate an event, it is automatically cleared by hardware.  
 0: No action  
 1: A break event is generated. MOE bit is cleared and BIF flag is set. Related interrupt or DMA transfer can occur if enabled.
- Bit 6 **TG**: Trigger generation  
 This bit is set by software in order to generate an event, it is automatically cleared by hardware.  
 0: No action  
 1: The TIF flag is set in TIMx\_SR register. Related interrupt or DMA transfer can occur if enabled.

- Bit 5 **COMG**: Capture/Compare control update generation  
This bit can be set by software, it is automatically cleared by hardware  
0: No action  
1: When CCPC bit is set, it allows to update CCxE, CCxNE and OCxM bits  
*Note: This bit acts only on channels having a complementary output.*
- Bit 4 **CC4G**: Capture/Compare 4 generation  
refer to CC1G description
- Bit 3 **CC3G**: Capture/Compare 3 generation  
refer to CC1G description
- Bit 2 **CC2G**: Capture/Compare 2 generation  
refer to CC1G description
- Bit 1 **CC1G**: Capture/Compare 1 generation  
This bit is set by software in order to generate an event, it is automatically cleared by hardware.  
0: No action  
1: A capture/compare event is generated on channel 1:  
**If channel CC1 is configured as output:**  
CC1IF flag is set, Corresponding interrupt or DMA request is sent if enabled.  
**If channel CC1 is configured as input:**  
The current value of the counter is captured in TIMx\_CCR1 register. The CC1IF flag is set, the corresponding interrupt or DMA request is sent if enabled. The CC1OF flag is set if the CC1IF flag was already high.
- Bit 0 **UG**: Update generation  
This bit can be set by software, it is automatically cleared by hardware.  
0: No action  
1: Reinitialize the counter and generates an update of the registers. Note that the prescaler counter is cleared too (anyway the prescaler ratio is not affected). The counter is cleared if the center-aligned mode is selected or if DIR=0 (upcounting), else it takes the auto-reload value (TIMx\_ARR) if DIR=1 (downcounting).

### 12.4.7 TIM1 capture/compare mode register 1 (TIMx\_CCMR1)

Address offset: 0x18

Reset value: 0x0000

The channels can be used in input (capture mode) or in output (compare mode). The direction of a channel is defined by configuring the corresponding CCxS bits. All the other bits of this register have a different function in input and in output mode. For a given bit, OCxx describes its function when the channel is configured in output, ICxx describes its function when the channel is configured in input. So you must take care that the same bit can have a different meaning for the input stage and for the output stage.

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
OC2 CE	OC2M[2:0]			OC2 PE	OC2 FE	CC2S[1:0]		OC1 CE	OC1M[2:0]			OC1 PE	OC1 FE	CC1S[1:0]	
IC2F[3:0]				IC2PSC[1:0]				IC1F[3:0]				IC1PSC[1:0]			
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

#### Output compare mode:

Bit 15 **OC2CE**: Output Compare 2 clear enable

Bits 14:12 **OC2M[2:0]**: Output Compare 2 mode

Bit 11 **OC2PE**: Output Compare 2 preload enable

Bit 10 **OC2FE**: Output Compare 2 fast enable

Bits 9:8 **CC2S[1:0]**: Capture/Compare 2 selection

This bit-field defines the direction of the channel (input/output) as well as the used input.

00: CC2 channel is configured as output

01: CC2 channel is configured as input, IC2 is mapped on TI2

10: CC2 channel is configured as input, IC2 is mapped on TI1

11: CC2 channel is configured as input, IC2 is mapped on TRC. This mode is working only if an internal trigger input is selected through the TS bit (TIMx\_SMCR register)

*Note:* CC2S bits are writable only when the channel is OFF (CC2E = '0' in TIMx\_CCER).

Bit 7 **OC1CE**: Output Compare 1 clear enable

OC1CE: Output Compare 1 Clear Enable

0: OC1Ref is not affected by the ETRF Input

1: OC1Ref is cleared as soon as a High level is detected on ETRF input

Bits 6:4 **OC1M**: Output Compare 1 mode

These bits define the behavior of the output reference signal OC1REF from which OC1 and OC1N are derived. OC1REF is active high whereas OC1 and OC1N active level depends on CC1P and CC1NP bits.

000: Frozen - The comparison between the output compare register TIMx\_CCR1 and the counter TIMx\_CNT has no effect on the outputs.(this mode is used to generate a timing base).

001: Set channel 1 to active level on match. OC1REF signal is forced high when the counter TIMx\_CNT matches the capture/compare register 1 (TIMx\_CCR1).

010: Set channel 1 to inactive level on match. OC1REF signal is forced low when the counter TIMx\_CNT matches the capture/compare register 1 (TIMx\_CCR1).

011: Toggle - OC1REF toggles when TIMx\_CNT=TIMx\_CCR1.

100: Force inactive level - OC1REF is forced low.

101: Force active level - OC1REF is forced high.

110: PWM mode 1 - In upcounting, channel 1 is active as long as TIMx\_CNT<TIMx\_CCR1 else inactive. In downcounting, channel 1 is inactive (OC1REF='0') as long as TIMx\_CNT>TIMx\_CCR1 else active (OC1REF='1').

111: PWM mode 2 - In upcounting, channel 1 is inactive as long as TIMx\_CNT<TIMx\_CCR1 else active. In downcounting, channel 1 is active as long as TIMx\_CNT>TIMx\_CCR1 else inactive.

*Note: 1: These bits can not be modified as long as LOCK level 3 has been programmed (LOCK bits in TIMx\_BDTR register) and CC1S='00' (the channel is configured in output).*

*2: In PWM mode 1 or 2, the OCREF level changes only when the result of the comparison changes or when the output compare mode switches from "frozen" mode to "PWM" mode.*

*3: On channels having a complementary output, this bit field is preloaded. If the CCPC bit is set in the TIMx\_CR2 register then the OC1M active bits take the new value from the preloaded bits only when a COM event is generated.*

Bit 3 **OC1PE**: Output Compare 1 preload enable

0: Preload register on TIMx\_CCR1 disabled. TIMx\_CCR1 can be written at anytime, the new value is taken in account immediately.

1: Preload register on TIMx\_CCR1 enabled. Read/Write operations access the preload register. TIMx\_CCR1 preload value is loaded in the active register at each update event.

*Note: 1: These bits can not be modified as long as LOCK level 3 has been programmed (LOCK bits in TIMx\_BDTR register) and CC1S='00' (the channel is configured in output).*

*2: The PWM mode can be used without validating the preload register only in one pulse mode (OPM bit set in TIMx\_CR1 register). Else the behavior is not guaranteed.*

Bit 2 **OC1FE**: Output Compare 1 fast enable

This bit is used to accelerate the effect of an event on the trigger in input on the CC output.  
0: CC1 behaves normally depending on counter and CCR1 values even when the trigger is ON. The minimum delay to activate CC1 output when an edge occurs on the trigger input is 5 clock cycles.

1: An active edge on the trigger input acts like a compare match on CC1 output. Then, OC is set to the compare level independently from the result of the comparison. Delay to sample the trigger input and to activate CC1 output is reduced to 3 clock cycles. OC1FE acts only if the channel is configured in PWM1 or PWM2 mode.

Bits 1:0 **CC1S**: Capture/Compare 1 selection

This bit-field defines the direction of the channel (input/output) as well as the used input.

00: CC1 channel is configured as output

01: CC1 channel is configured as input, IC1 is mapped on TI1

10: CC1 channel is configured as input, IC1 is mapped on TI2

11: CC1 channel is configured as input, IC1 is mapped on TRC. This mode is working only if an internal trigger input is selected through TS bit (TIMx\_SMCR register)

*Note: CC1S bits are writable only when the channel is OFF (CC1E = '0' in TIMx\_CCER).*

## Input capture mode

Bits 15:12 **IC2F**: Input capture 2 filter

Bits 11:10 **IC2PSC[1:0]**: Input capture 2 prescaler

Bits 9:8 **CC2S**: Capture/Compare 2 selection

This bit-field defines the direction of the channel (input/output) as well as the used input.

00: CC2 channel is configured as output

01: CC2 channel is configured as input, IC2 is mapped on TI2

10: CC2 channel is configured as input, IC2 is mapped on TI1

11: CC2 channel is configured as input, IC2 is mapped on TRC. This mode is working only if an internal trigger input is selected through TS bit (TIMx\_SMCR register)

*Note: CC2S bits are writable only when the channel is OFF (CC2E = '0' in TIMx\_CCER).*

Bits 7:4 **IC1F[3:0]**: Input capture 1 filter

This bit-field defines the frequency used to sample TI1 input and the length of the digital filter applied to TI1. The digital filter is made of an event counter in which N events are needed to validate a transition on the output:

0000: No filter, sampling is done at  $f_{DTS}$

0001:  $f_{SAMPLING} = f_{CK\_INT}$ , N=2

0010:  $f_{SAMPLING} = f_{CK\_INT}$ , N=4

0011:  $f_{SAMPLING} = f_{CK\_INT}$ , N=8

0100:  $f_{SAMPLING} = f_{DTS}/2$ , N=6

0101:  $f_{SAMPLING} = f_{DTS}/2$ , N=8

0110:  $f_{SAMPLING} = f_{DTS}/4$ , N=6

0111:  $f_{SAMPLING} = f_{DTS}/4$ , N=8

1000:  $f_{SAMPLING} = f_{DTS}/8$ , N=6

1001:  $f_{SAMPLING} = f_{DTS}/8$ , N=8

1010:  $f_{SAMPLING} = f_{DTS}/16$ , N=5

1011:  $f_{SAMPLING} = f_{DTS}/16$ , N=6

1100:  $f_{SAMPLING} = f_{DTS}/16$ , N=8

1101:  $f_{SAMPLING} = f_{DTS}/32$ , N=5

1110:  $f_{SAMPLING} = f_{DTS}/32$ , N=6

1111:  $f_{SAMPLING} = f_{DTS}/32$ , N=8

Bits 3:2 **IC1PSC**: Input capture 1 prescaler

This bit-field defines the ratio of the prescaler acting on CC1 input (IC1).

The prescaler is reset as soon as CC1E='0' (TIMx\_CCER register).

00: no prescaler, capture is done each time an edge is detected on the capture input

01: capture is done once every 2 events

10: capture is done once every 4 events

11: capture is done once every 8 events

Bits 1:0 **CC1S**: Capture/Compare 1 Selection

This bit-field defines the direction of the channel (input/output) as well as the used input.

00: CC1 channel is configured as output

01: CC1 channel is configured as input, IC1 is mapped on TI1

10: CC1 channel is configured as input, IC1 is mapped on TI2

11: CC1 channel is configured as input, IC1 is mapped on TRC. This mode is working only if an internal trigger input is selected through TS bit (TIMx\_SMCR register)

Note: CC1S bits are writable only when the channel is OFF (CC1E = '0' in TIMx\_CCER).

### 12.4.8 TIM1 capture/compare mode register 2 (TIMx\_CCMR2)

Address offset: 0x1C

Reset value: 0x0000

Refer to the above CCMR1 register description.

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
OC4 CE	OC4M[2:0]			OC4 PE	OC4 FE	CC4S[1:0]		OC3 CE	OC3M[2:0]			OC3 PE	OC3 FE	CC3S[1:0]	
IC4F[3:0]				IC4PSC[1:0]				IC3F[3:0]				IC3PSC[1:0]			
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

#### Output compare mode

Bit 15 **OC4CE**: Output compare 4 clear enable

Bits 14:12 **OC4M**: Output compare 4 mode

Bit 11 **OC4PE**: Output compare 4 preload enable

Bit 10 **OC4FE**: Output compare 4 fast enable

Bits 9:8 **CC4S**: Capture/Compare 4 selection

This bit-field defines the direction of the channel (input/output) as well as the used input.

00: CC4 channel is configured as output

01: CC4 channel is configured as input, IC4 is mapped on TI4

10: CC4 channel is configured as input, IC4 is mapped on TI3

11: CC4 channel is configured as input, IC4 is mapped on TRC. This mode is working only if an internal trigger input is selected through TS bit (TIMx\_SMCR register)

Note: CC4S bits are writable only when the channel is OFF (CC4E = '0' in TIMx\_CCER).

Bit 7 **OC3CE**: Output compare 3 clear enable

Bits 6:4 **OC3M**: Output compare 3 mode

Bit 3 **OC3PE**: Output compare 3 preload enable

Bit 2 **OC3FE**: Output compare 3 fast enable

Bits 1:0 **CC3S**: Capture/Compare 3 selection

This bit-field defines the direction of the channel (input/output) as well as the used input.

00: CC3 channel is configured as output

01: CC3 channel is configured as input, IC3 is mapped on TI3

10: CC3 channel is configured as input, IC3 is mapped on TI4

11: CC3 channel is configured as input, IC3 is mapped on TRC. This mode is working only if an internal trigger input is selected through TS bit (TIMx\_SMCR register)

Note: CC3S bits are writable only when the channel is OFF (CC3E = '0' in TIMx\_CCER).

### Input capture mode

Bits 15:12 **IC4F**: Input capture 4 filter

Bits 11:10 **IC4PSC**: Input capture 4 prescaler

Bits 9:8 **CC4S**: Capture/Compare 4 selection

This bit-field defines the direction of the channel (input/output) as well as the used input.

00: CC4 channel is configured as output

01: CC4 channel is configured as input, IC4 is mapped on TI4

10: CC4 channel is configured as input, IC4 is mapped on TI3

11: CC4 channel is configured as input, IC4 is mapped on TRC. This mode is working only if an internal trigger input is selected through TS bit (TIMx\_SMCR register)

*Note: CC4S bits are writable only when the channel is OFF (CC4E = '0' in TIMx\_CCER).*

Bits 7:4 **IC3F**: Input capture 3 filter

Bits 3:2 **IC3PSC**: Input capture 3 prescaler

Bits 1:0 **CC3S**: Capture/compare 3 selection

This bit-field defines the direction of the channel (input/output) as well as the used input.

00: CC3 channel is configured as output

01: CC3 channel is configured as input, IC3 is mapped on TI3

10: CC3 channel is configured as input, IC3 is mapped on TI4

11: CC3 channel is configured as input, IC3 is mapped on TRC. This mode is working only if an internal trigger input is selected through TS bit (TIMx\_SMCR register)

*Note: CC3S bits are writable only when the channel is OFF (CC3E = '0' in TIMx\_CCER).*

### 12.4.9 TIM1 capture/compare enable register (TIMx\_CCER)

Address offset: 0x20

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved		CC4P	CC4E	CC3NP	CC3NE	CC3P	CC3E	CC2NP	CC2NE	CC2P	CC2E	CC1NP	CC1NE	CC1P	CC1E
		rW	rW	rW	rW	rW	rW	rW	rW	rW	rW	rW	rW	rW	rW

Bits 15:14 Reserved, must be kept at reset value.

Bit 13 **CC4P**: Capture/Compare 4 output polarity  
refer to CC1P description

Bit 12 **CC4E**: Capture/Compare 4 output enable  
refer to CC1E description

Bit 11 **CC3NP**: Capture/Compare 3 complementary output polarity  
refer to CC1NP description

Bit 10 **CC3NE**: Capture/Compare 3 complementary output enable  
refer to CC1NE description

Bit 9 **CC3P**: Capture/Compare 3 output polarity  
refer to CC1P description

Bit 8 **CC3E**: Capture/Compare 3 output enable  
refer to CC1E description

- Bit 7 **CC2NP**: Capture/Compare 2 complementary output polarity  
refer to CC1NP description
- Bit 6 **CC2NE**: Capture/Compare 2 complementary output enable  
refer to CC1NE description
- Bit 5 **CC2P**: Capture/Compare 2 output polarity  
refer to CC1P description
- Bit 4 **CC2E**: Capture/Compare 2 output enable  
refer to CC1E description
- Bit 3 **CC1NP**: Capture/Compare 1 complementary output polarity  
CC1 channel configured as output:  
0: OC1N active high.  
1: OC1N active low.  
CC1 channel configured as input:  
This bit is used in conjunction with CC1P to define the polarity of TI1FP1 and TI2FP1. Refer to CC1P description.
- Note: On channels having a complementary output, this bit is preloaded. If the CCPC bit is set in the TIMx\_CR2 register then the CC1NP active bit takes the new value from the preloaded bit only when a Commutation event is generated.*
- Note: This bit is not writable as soon as LOCK level 2 or 3 has been programmed (LOCK bits in TIMx\_BDTR register) and CC1S="00" (the channel is configured in output).*
- Bit 2 **CC1NE**: Capture/Compare 1 complementary output enable  
0: Off - OC1N is not active. OC1N level is then function of MOE, OSSI, OSSR, OIS1, OIS1N and CC1E bits.  
1: On - OC1N signal is output on the corresponding output pin depending on MOE, OSSI, OSSR, OIS1, OIS1N and CC1E bits.
- Note: On channels having a complementary output, this bit is preloaded. If the CCPC bit is set in the TIMx\_CR2 register then the CC1NE active bit takes the new value from the preloaded bit only when a Commutation event is generated.*



Bit 1 **CC1P**: Capture/Compare 1 output polarity

**CC1 channel configured as output:**

0: OC1 active high

1: OC1 active low

**CC1 channel configured as input:**

CC1NP/CC1P bits select the active polarity of TI1FP1 and TI2FP1 for trigger or capture operations.

00: non-inverted/rising edge

The circuit is sensitive to TIxFP1 rising edge (capture or trigger operations in reset, external clock or trigger mode), TIxFP1 is not inverted (trigger operation in gated mode or encoder mode).

01: inverted/falling edge

The circuit is sensitive to TIxFP1 falling edge (capture or trigger operations in reset, external clock or trigger mode), TIxFP1 is inverted (trigger operation in gated mode or encoder mode).

10: reserved, do not use this configuration.

11: non-inverted/both edges

The circuit is sensitive to both TIxFP1 rising and falling edges (capture or trigger operations in reset, external clock or trigger mode), TIxFP1 is not inverted (trigger operation in gated mode). This configuration must not be used in encoder mode.

*Note: On channels having a complementary output, this bit is preloaded. If the CCPC bit is set in the TIMx\_CR2 register then the CC1P active bit takes the new value from the preloaded bit only when a Commutation event is generated.*

*Note: This bit is not writable as soon as LOCK level 2 or 3 has been programmed (LOCK bits in TIMx\_BDTR register).*

Bit 0 **CC1E**: Capture/Compare 1 output enable

**CC1 channel configured as output:**

0: Off - OC1 is not active. OC1 level is then function of MOE, OSS1, OSSR, OIS1, OIS1N and CC1NE bits.

1: On - OC1 signal is output on the corresponding output pin depending on MOE, OSS1, OSSR, OIS1, OIS1N and CC1NE bits.

**CC1 channel configured as input:**

This bit determines if a capture of the counter value can actually be done into the input capture/compare register 1 (TIMx\_CCR1) or not.

0: Capture disabled.

1: Capture enabled.

*Note: On channels having a complementary output, this bit is preloaded. If the CCPC bit is set in the TIMx\_CR2 register then the CC1E active bit takes the new value from the preloaded bit only when a Commutation event is generated.*

**Table 51. Output control bits for complementary OCx and OCxN channels with break feature**

Control bits					Output states <sup>(1)</sup>				
MOE bit	OSSI bit	OSSR bit	CCxE bit	CCxNE bit	OCx output state	OCxN output state			
1	X	0	0	0	Output Disabled (not driven by the timer), OCx=0, OCx_EN=0	Output Disabled (not driven by the timer), OCxN=0, OCxN_EN=0			
		0	0	1	Output Disabled (not driven by the timer), OCx=0, OCx_EN=0	OCxREF + Polarity OCxN=OCxREF xor CCxNP, OCxN_EN=1			
		0	1	0	OCxREF + Polarity OCx=OCxREF xor CCxP, OCx_EN=1	Output Disabled (not driven by the timer) OCxN=0, OCxN_EN=0			
		0	1	1	OCREF + Polarity + dead-time OCx_EN=1	Complementary to OCREF (not OCREF) + Polarity + dead-time OCxN_EN=1			
		1	0	0	Output Disabled (not driven by the timer) OCx=CCxP, OCx_EN=0	Output Disabled (not driven by the timer) OCxN=CCxNP, OCxN_EN=0			
		1	0	1	Off-State (output enabled with inactive state) OCx=CCxP, OCx_EN=1	OCxREF + Polarity OCxN=OCxREF xor CCxNP, OCxN_EN=1			
		1	1	0	OCxREF + Polarity OCx=OCxREF xor CCxP, OCx_EN=1	Off-State (output enabled with inactive state) OCxN=CCxNP, OCxN_EN=1			
		1	1	1	OCREF + Polarity + dead-time OCx_EN=1	Complementary to OCREF (not OCREF) + Polarity + dead-time OCxN_EN=1			
0	X	0	0	0	Output Disabled (not driven by the timer) OCx=CCxP, OCx_EN=0	Output Disabled (not driven by the timer) OCxN=CCxNP, OCxN_EN=0			
					0	0	1	Output Disabled (not driven by the timer)	Asynchronously: OCx=CCxP, OCx_EN=0, OCxN=CCxNP, OCxN_EN=0 Then if the clock is present: OCx=OISx and OCxN=OISxN after a dead-time, assuming that OISx and OISxN do not correspond to OCx and OCxN both in active state.
					0	1	0		
					0	1	1		
					1	0	0	Output Disabled (not driven by the timer) OCx=CCxP, OCx_EN=0	Output Disabled (not driven by the timer) OCxN=CCxNP, OCxN_EN=0
					1	0	1	Off-State (output enabled with inactive state)	
					1	1	0	Asynchronously: OCx=CCxP, OCx_EN=1, OCxN=CCxNP, OCxN_EN=1	
					1	1	1	Then if the clock is present: OCx=OISx and OCxN=OISxN after a dead-time, assuming that OISx and OISxN do not correspond to OCx and OCxN both in active state	

1. When both outputs of a channel are not used (CCxE = CCxNE = 0), the OISx, OISxN, CCxP and CCxNP bits must be kept cleared.

Note: The state of the external I/O pins connected to the complementary OCx and OCxN channels depends on the OCx and OCxN channel state and the GPIO registers.

### 12.4.10 TIM1 counter (TIMx\_CNT)

Address offset: 0x24

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
CNT[15:0]															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 15:0 **CNT[15:0]**: Counter value

### 12.4.11 TIM1 prescaler (TIMx\_PSC)

Address offset: 0x28

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
PSC[15:0]															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 15:0 **PSC[15:0]**: Prescaler value

The counter clock frequency (CK\_CNT) is equal to  $f_{CK\_PSC} / (PSC[15:0] + 1)$ .  
 PSC contains the value to be loaded in the active prescaler register at each update event (including when the counter is cleared through UG bit of TIMx\_EGR register or through trigger controller when configured in “reset mode”).

### 12.4.12 TIM1 auto-reload register (TIMx\_ARR)

Address offset: 0x2C

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
ARR[15:0]															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 15:0 **ARR[15:0]**: Auto-reload value

ARR is the value to be loaded in the actual auto-reload register.  
 Refer to [Section 12.3.1: Time-base unit on page 244](#) for more details about ARR update and behavior.  
 The counter is blocked while the auto-reload value is null.

### 12.4.13 TIM1 repetition counter register (TIMx\_RCR)

Address offset: 0x30

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
Reserved								REP[7:0]								
								rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 15:8 Reserved, must be kept at reset value.

Bits 7:0 **REP[7:0]**: Repetition counter value

These bits allow the user to set-up the update rate of the compare registers (i.e. periodic transfers from preload to active registers) when preload registers are enable, as well as the update interrupt generation rate, if this interrupt is enable.

Each time the REP\_CNT related downcounter reaches zero, an update event is generated and it restarts counting from REP value. As REP\_CNT is reloaded with REP value only at the repetition update event U\_RC, any write to the TIMx\_RCR register is not taken in account until the next repetition update event.

It means in PWM mode (REP+1) corresponds to:

- the number of PWM periods in edge-aligned mode
- the number of half PWM period in center-aligned mode.

### 12.4.14 TIM1 capture/compare register 1 (TIMx\_CCR1)

Address offset: 0x34

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
CCR1[15:0]															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 15:0 **CCR1[15:0]**: Capture/Compare 1 value

**If channel CC1 is configured as output:**

CCR1 is the value to be loaded in the actual capture/compare 1 register (preload value).

It is loaded permanently if the preload feature is not selected in the TIMx\_CCMR1 register (bit OC1PE). Else the preload value is copied in the active capture/compare 1 register when an update event occurs.

The active capture/compare register contains the value to be compared to the counter TIMx\_CNT and signaled on OC1 output.

**If channel CC1 is configured as input:**

CCR1 is the counter value transferred by the last input capture 1 event (IC1).

### 12.4.15 TIM1 capture/compare register 2 (TIMx\_CCR2)

Address offset: 0x38

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
CCR2[15:0]															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 15:0 **CCR2[15:0]**: Capture/Compare 2 value

**If channel CC2 is configured as output:**

CCR2 is the value to be loaded in the actual capture/compare 2 register (preload value). It is loaded permanently if the preload feature is not selected in the TIMx\_CCMR2 register (bit OC2PE). Else the preload value is copied in the active capture/compare 2 register when an update event occurs.

The active capture/compare register contains the value to be compared to the counter TIMx\_CNT and signalled on OC2 output.

**If channel CC2 is configured as input:**

CCR2 is the counter value transferred by the last input capture 2 event (IC2).

### 12.4.16 TIM1 capture/compare register 3 (TIMx\_CCR3)

Address offset: 0x3C

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
CCR3[15:0]															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 15:0 **CCR3[15:0]**: Capture/Compare value

**If channel CC3 is configured as output:**

CCR3 is the value to be loaded in the actual capture/compare 3 register (preload value). It is loaded permanently if the preload feature is not selected in the TIMx\_CCMR3 register (bit OC3PE). Else the preload value is copied in the active capture/compare 3 register when an update event occurs.

The active capture/compare register contains the value to be compared to the counter TIMx\_CNT and signalled on OC3 output.

**If channel CC3 is configured as input:**

CCR3 is the counter value transferred by the last input capture 3 event (IC3).

### 12.4.17 TIM1 capture/compare register 4 (TIMx\_CCR4)

Address offset: 0x40

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
CCR4[15:0]															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 15:0 **CCR4[15:0]**: Capture/Compare value

**If channel CC4 is configured as output:**

CCR4 is the value to be loaded in the actual capture/compare 4 register (preload value). It is loaded permanently if the preload feature is not selected in the TIMx\_CCMR4 register (bit OC4PE). Else the preload value is copied in the active capture/compare 4 register when an update event occurs.

The active capture/compare register contains the value to be compared to the counter TIMx\_CNT and signalled on OC4 output.

**If channel CC4 is configured as input:**

CCR4 is the counter value transferred by the last input capture 4 event (IC4).

### 12.4.18 TIM1 break and dead-time register (TIMx\_BDTR)

Address offset: 0x44

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
MOE	AOE	BKP	BKE	OSSR	OSSI	LOCK[1:0]		DTG[7:0]							
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

*Note:* As the bits AOE, BKP, BKE, OSSI, OSSR and DTG[7:0] can be write-locked depending on the LOCK configuration, it can be necessary to configure all of them during the first write access to the TIMx\_BDTR register.

Bit 15 **MOE**: Main output enable

This bit is cleared asynchronously by hardware as soon as the break input is active. It is set by software or automatically depending on the AOE bit. It is acting only on the channels which are configured in output.

0: OC and OCN outputs are disabled or forced to idle state.

1: OC and OCN outputs are enabled if their respective enable bits are set (CCxE, CCxNE in TIMx\_CCER register).

See OC/OCN enable description for more details ([Section 12.4.9: TIM1 capture/compare enable register \(TIMx\\_CCER\) on page 298](#)).

Bit 14 **AOE**: Automatic output enable

0: MOE can be set only by software

1: MOE can be set by software or automatically at the next update event (if the break input is not be active)

*Note:* This bit can not be modified as long as LOCK level 1 has been programmed (LOCK bits in TIMx\_BDTR register).

Bit 13 **BKP**: Break polarity

- 0: Break input BRK is active low
- 1: Break input BRK is active high

*Note: This bit can not be modified as long as LOCK level 1 has been programmed (LOCK bits in TIMx\_BDTR register).*

*Note: Any write operation to this bit takes a delay of 1 APB clock cycle to become effective.*

Bit 12 **BKE**: Break enable

- 0: Break inputs (BRK and CSS clock failure event) disabled
- 1: Break inputs (BRK and CSS clock failure event) enabled

*Note: This bit cannot be modified when LOCK level 1 has been programmed (LOCK bits in TIMx\_BDTR register).*

*Note: Any write operation to this bit takes a delay of 1 APB clock cycle to become effective.*

Bit 11 **OSSR**: Off-state selection for Run mode

This bit is used when MOE=1 on channels having a complementary output which are configured as outputs. OSSR is not implemented if no complementary output is implemented in the timer.

See OC/OCN enable description for more details ([Section 12.4.9: TIM1 capture/compare enable register \(TIMx\\_CCER\) on page 298](#)).

- 0: When inactive, OC/OCN outputs are disabled (OC/OCN enable output signal=0).
- 1: When inactive, OC/OCN outputs are enabled with their inactive level as soon as CCxE=1 or CCxNE=1. Then, OC/OCN enable output signal=1

*Note: This bit can not be modified as soon as the LOCK level 2 has been programmed (LOCK bits in TIMx\_BDTR register).*

Bit 10 **OSSI**: Off-state selection for Idle mode

This bit is used when MOE=0 on channels configured as outputs.

See OC/OCN enable description for more details ([Section 12.4.9: TIM1 capture/compare enable register \(TIMx\\_CCER\) on page 298](#)).

- 0: When inactive, OC/OCN outputs are disabled (OC/OCN enable output signal=0).
- 1: When inactive, OC/OCN outputs are forced first with their idle level as soon as CCxE=1 or CCxNE=1. OC/OCN enable output signal=1

*Note: This bit can not be modified as soon as the LOCK level 2 has been programmed (LOCK bits in TIMx\_BDTR register).*

Bits 9:8 **LOCK[1:0]**: Lock configuration

These bits offer a write protection against software errors.

00: LOCK OFF - No bit is write protected.

01: LOCK Level 1 = DTG bits in TIMx\_BDTR register, OISx and OISxN bits in TIMx\_CR2 register and BKE/BKP/AOE bits in TIMx\_BDTR register can no longer be written.

10: LOCK Level 2 = LOCK Level 1 + CC Polarity bits (CCxP/CCxNP bits in TIMx\_CCER register, as long as the related channel is configured in output through the CCxS bits) as well as OSSR and OSSI bits can no longer be written.

11: LOCK Level 3 = LOCK Level 2 + CC Control bits (OCxM and OCxPE bits in TIMx\_CCMRx registers, as long as the related channel is configured in output through the CCxS bits) can no longer be written.

*Note: The LOCK bits can be written only once after the reset. Once the TIMx\_BDTR register has been written, their content is frozen until the next reset.*

Bits 7:0 **DTG[7:0]**: Dead-time generator setup

This bit-field defines the duration of the dead-time inserted between the complementary outputs. DT correspond to this duration.

DTG[7:5]=0xx => DT=DTG[7:0]x t<sub>dtg</sub> with t<sub>dtg</sub>=t<sub>DTS</sub>.

DTG[7:5]=10x => DT=(64+DTG[5:0])x t<sub>dtg</sub> with T<sub>dtg</sub>=2x t<sub>DTS</sub>.

DTG[7:5]=110 => DT=(32+DTG[4:0])x t<sub>dtg</sub> with T<sub>dtg</sub>=8x t<sub>DTS</sub>.

DTG[7:5]=111 => DT=(32+DTG[4:0])x t<sub>dtg</sub> with T<sub>dtg</sub>=16x t<sub>DTS</sub>.

Example if T<sub>DTS</sub>=125ns (8MHz), dead-time possible values are:

0 to 15875 ns by 125 ns steps,

16 us to 31750 ns by 250 ns steps,

32 us to 63us by 1 us steps,

64 us to 126 us by 2 us steps

*Note: This bit-field can not be modified as long as LOCK level 1, 2 or 3 has been programmed (LOCK bits in TIMx\_BDTR register).*

### 12.4.19 TIM1 DMA control register (TIMx\_DCR)

Address offset: 0x48

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved			DBL[4:0]					Reserved			DBA[4:0]				
			rw	rw	rw	rw	rw				rw	rw	rw	rw	rw

Bits 15:13 Reserved, must be kept at reset value.

Bits 12:8 **DBL[4:0]**: DMA burst length

This 5-bit vector defines the number of DMA transfers (the timer detects a burst transfer when a read or a write access to the TIMx\_DMAR register address is performed).

the TIMx\_DMAR address)

00000: 1 transfer

00001: 2 transfers

00010: 3 transfers

...

10001: 18 transfers

Bits 7:5 Reserved, must be kept at reset value.

Bits 4:0 **DBA[4:0]**: DMA base address

This 5-bits vector defines the base-address for DMA transfers (when read/write access are done through the TIMx\_DMAR address). DBA is defined as an offset starting from the address of the TIMx\_CR1 register.

Example:

00000: TIMx\_CR1,

00001: TIMx\_CR2,

00010: TIMx\_SMCR,

...

**Example:** Let us consider the following transfer: DBL = 7 transfers and DBA = TIMx\_CR1. In this case the transfer is done to/from 7 registers starting from the TIMx\_CR1 address.



### 12.4.20 TIM1 DMA address for full transfer (TIMx\_DMAR)

Address offset: 0x4C

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
DMAB[15:0]															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 15:0 **DMAB[15:0]**: DMA register for burst accesses

A read or write operation to the DMAR register accesses the register located at the address  
 $(TIMx\_CR1 \text{ address}) + (DBA + \text{DMA index}) \times 4$

where TIMx\_CR1 address is the address of the control register 1, DBA is the DMA base address configured in TIMx\_DCR register, DMA index is automatically controlled by the DMA transfer, and ranges from 0 to DBL (DBL configured in TIMx\_DCR).

#### Example of how to use the DMA burst feature

In this example the timer DMA burst feature is used to update the contents of the CCRx registers (x = 2, 3, 4) with the DMA transferring half words into the CCRx registers.

This is done in the following steps:

1. Configure the corresponding DMA channel as follows:
  - DMA channel peripheral address is the DMAR register address
  - DMA channel memory address is the address of the buffer in the RAM containing the data to be transferred by DMA into CCRx registers.
  - Number of data to transfer = 3 (See note below).
  - Circular mode disabled.
2. Configure the DCR register by configuring the DBA and DBL bit fields as follows:  
 DBL = 3 transfers, DBA = 0xE.
3. Enable the TIMx update DMA request (set the UDE bit in the DIER register).
4. Enable TIMx
5. Enable the DMA channel

*Note: This example is for the case where every CCRx register to be updated once. If every CCRx register is to be updated twice for example, the number of data to transfer should be 6. Let's take the example of a buffer in the RAM containing data1, data2, data3, data4, data5 and data6. The data is transferred to the CCRx registers as follows: on the first update DMA request, data1 is transferred to CCR2, data2 is transferred to CCR3, data3 is transferred to CCR4 and on the second update DMA request, data4 is transferred to CCR2, data5 is transferred to CCR3 and data6 is transferred to CCR4.*



Table 52. TIM1 register map and reset values (continued)

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0																					
0x2C	TIMx_ARR	Reserved																ARR[15:0]																																				
	Reset value																	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0					
0x30	TIMx_RCR	Reserved																							REP[7:0]																													
	Reset value																								0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x34	TIMx_CCR1	Reserved																CCR1[15:0]																																				
	Reset value																	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0					
0x38	TIMx_CCR2	Reserved																CCR2[15:0]																																				
	Reset value																	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0				
0x3C	TIMx_CCR3	Reserved																CCR3[15:0]																																				
	Reset value																	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0				
0x40	TIMx_CCR4	Reserved																CCR4[15:0]																																				
	Reset value																	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0				
0x44	TIMx_BDTR	Reserved																MOE	AOE	BKP	BKE	OSSR	OSSI	LOCK [1:0]	DT[7:0]																													
	Reset value																	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0				
0x48	TIMx_DCR	Reserved																DBL[4:0]				Reserved	DBA[4:0]																															
	Reset value																	0	0	0	0		0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0				
0x4C	TIMx_DMAR	Reserved																DMAB[15:0]																																				
	Reset value																	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0				

Refer to [Table 1 on page 38](#) for the register boundary addresses.

## 13 General-purpose timers (TIM2 to TIM5)

### 13.1 TIM2 to TIM5 introduction

The general-purpose timers consist of a 16-bit or 32-bit auto-reload counter driven by a programmable prescaler.

They may be used for a variety of purposes, including measuring the pulse lengths of input signals (*input capture*) or generating output waveforms (*output compare and PWM*).

Pulse lengths and waveform periods can be modulated from a few microseconds to several milliseconds using the timer prescaler and the RCC clock controller prescalers.

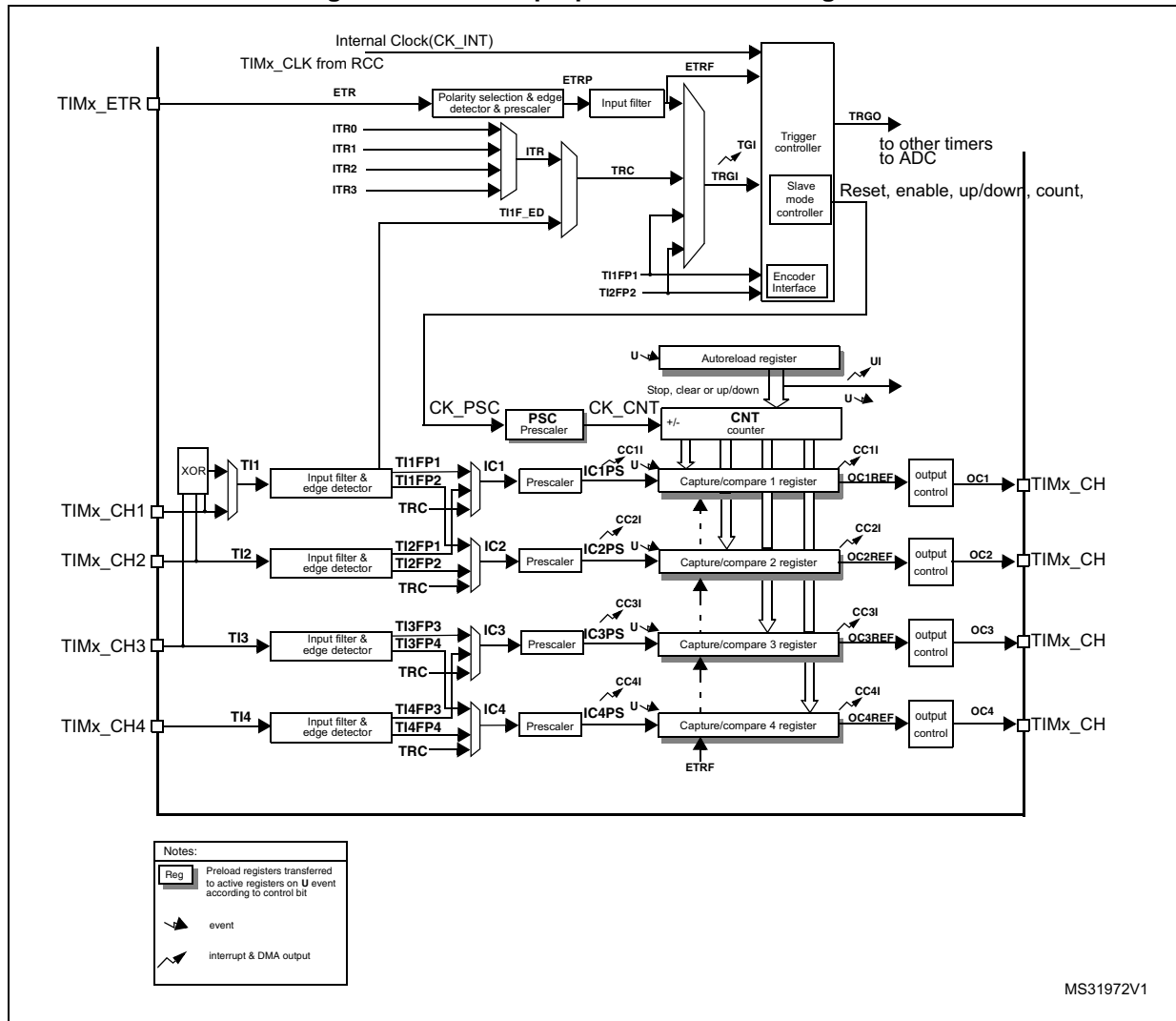
The timers are completely independent, and do not share any resources. They can be synchronized together as described in [Section 13.3.15](#).

### 13.2 TIM2 to TIM5 main features

General-purpose TIMx timer features include:

- 16-bit (TIM3 and TIM4) or 32-bit (TIM2 and TIM5) up, down, up/down auto-reload counter.
- 16-bit programmable prescaler used to divide (also “on the fly”) the counter clock frequency by any factor between 1 and 65536.
- Up to 4 independent channels for:
  - Input capture
  - Output compare
  - PWM generation (Edge- and Center-aligned modes)
  - One-pulse mode output
- Synchronization circuit to control the timer with external signals and to interconnect several timers.
- Interrupt/DMA generation on the following events:
  - Update: counter overflow/underflow, counter initialization (by software or internal/external trigger)
  - Trigger event (counter start, stop, initialization or count by internal/external trigger)
  - Input capture
  - Output compare
- Supports incremental (quadrature) encoder and hall-sensor circuitry for positioning purposes
- Trigger input for external clock or cycle-by-cycle current management

Figure 87. General-purpose timer block diagram



### 13.3 TIM2 to TIM5 functional description

#### 13.3.1 Time-base unit

The main block of the programmable timer is a 16-bit/32-bit counter with its related auto-reload register. The counter can count up. The counter clock can be divided by a prescaler.

The counter, the auto-reload register and the prescaler register can be written or read by software. This is true even when the counter is running.

The time-base unit includes:

- Counter Register (TIMx\_CNT)
- Prescaler Register (TIMx\_PSC):
- Auto-Reload Register (TIMx\_ARR)

The auto-reload register is preloaded. Writing to or reading from the auto-reload register accesses the preload register. The content of the preload register are transferred into the shadow register permanently or at each update event (UEV), depending on the auto-reload preload enable bit (ARPE) in TIMx\_CR1 register. The update event is sent when the counter reaches the overflow (or underflow when downcounting) and if the UDIS bit equals 0 in the TIMx\_CR1 register. It can also be generated by software. The generation of the update event is described in detail for each configuration.

The counter is clocked by the prescaler output CK\_CNT, which is enabled only when the counter enable bit (CEN) in TIMx\_CR1 register is set (refer also to the slave mode controller description to get more details on counter enabling).

Note that the actual counter enable signal CNT\_EN is set 1 clock cycle after CEN.

**Prescaler description**

The prescaler can divide the counter clock frequency by any factor between 1 and 65536. It is based on a 16-bit counter controlled through a 16-bit/32-bit register (in the TIMx\_PSC register). It can be changed on the fly as this control register is buffered. The new prescaler ratio is taken into account at the next update event.

Figure 88 and Figure 89 give some examples of the counter behavior when the prescaler ratio is changed on the fly:

**Figure 88. Counter timing diagram with prescaler division change from 1 to 2**

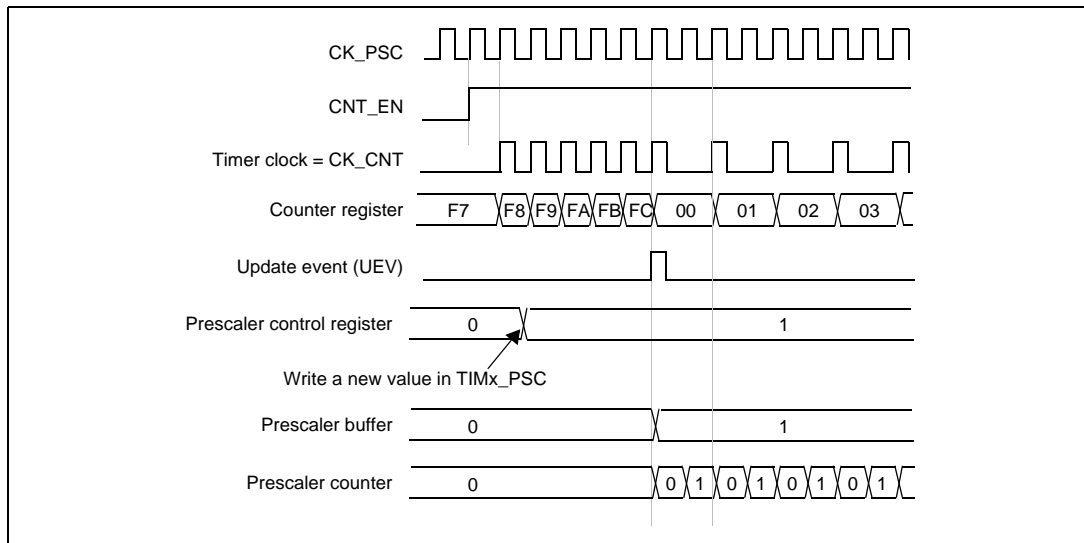
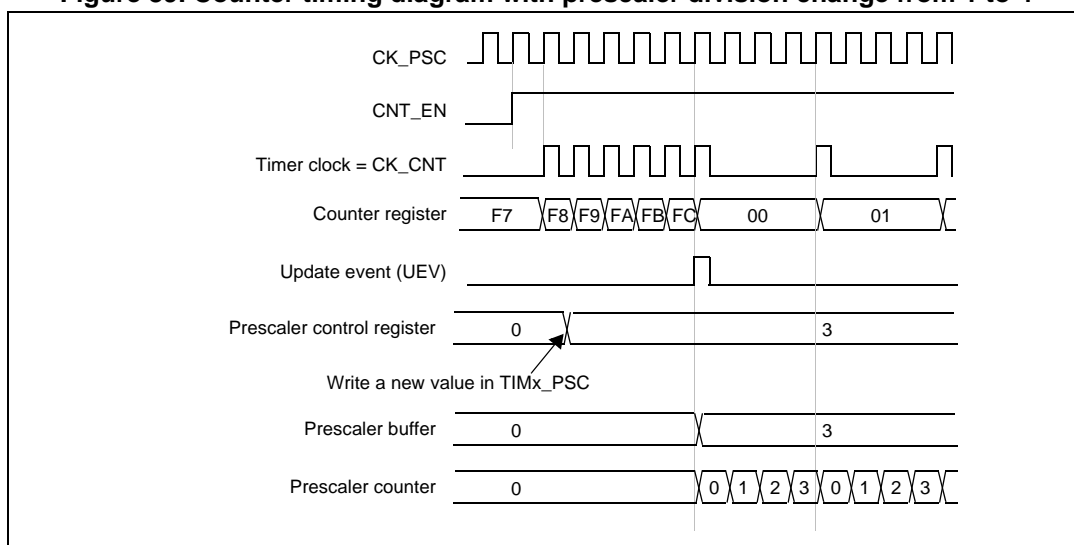


Figure 89. Counter timing diagram with prescaler division change from 1 to 4



### 13.3.2 Counter modes

#### Upcounting mode

In upcounting mode, the counter counts from 0 to the auto-reload value (content of the TIMx\_ARR register), then restarts from 0 and generates a counter overflow event.

An Update event can be generated at each counter overflow or by setting the UG bit in the TIMx\_EGR register (by software or by using the slave mode controller).

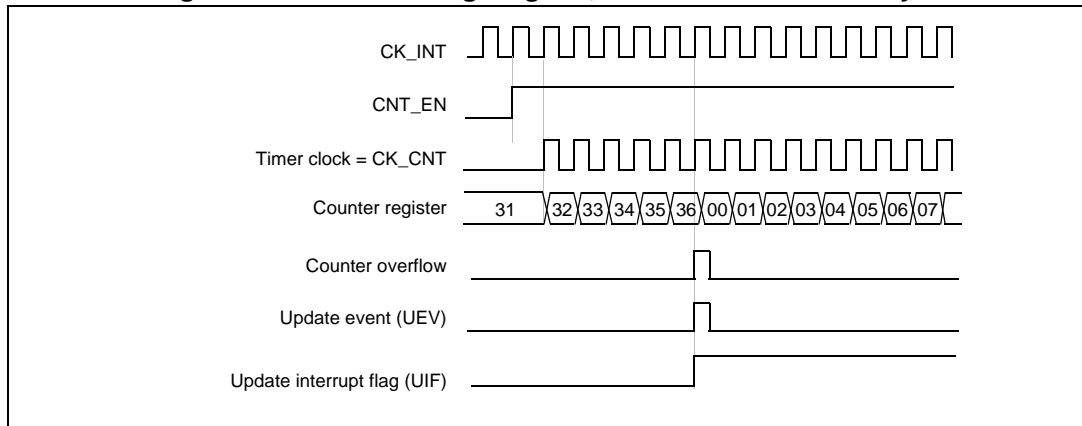
The UEV event can be disabled by software by setting the UDIS bit in TIMx\_CR1 register. This is to avoid updating the shadow registers while writing new values in the preload registers. Then no update event occurs until the UDIS bit has been written to 0. However, the counter restarts from 0, as well as the counter of the prescaler (but the prescale rate does not change). In addition, if the URS bit (update request selection) in TIMx\_CR1 register is set, setting the UG bit generates an update event UEV but without setting the UIF flag (thus no interrupt or DMA request is sent). This is to avoid generating both update and capture interrupts when clearing the counter on the capture event.

When an update event occurs, all the registers are updated and the update flag (UIF bit in TIMx\_SR register) is set (depending on the URS bit):

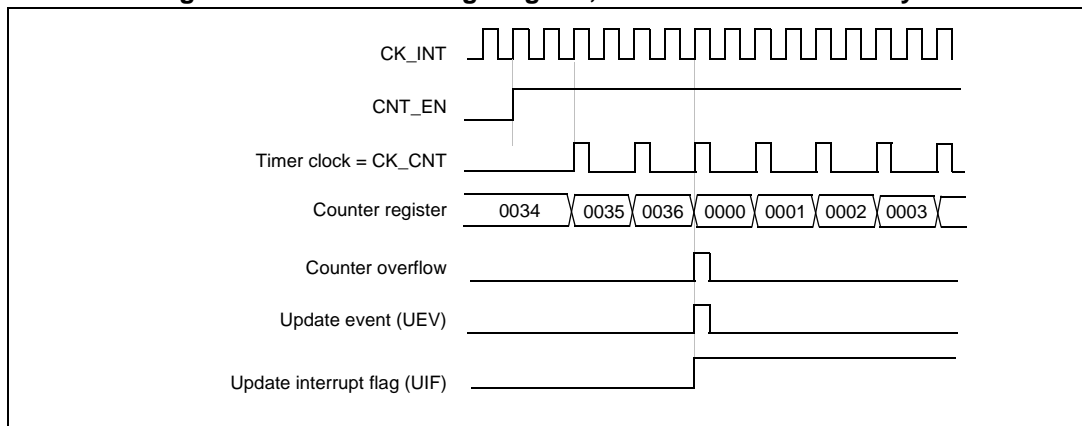
- The buffer of the prescaler is reloaded with the preload value (content of the TIMx\_PSC register)
- The auto-reload shadow register is updated with the preload value (TIMx\_ARR)

The following figures show some examples of the counter behavior for different clock frequencies when TIMx\_ARR=0x36.

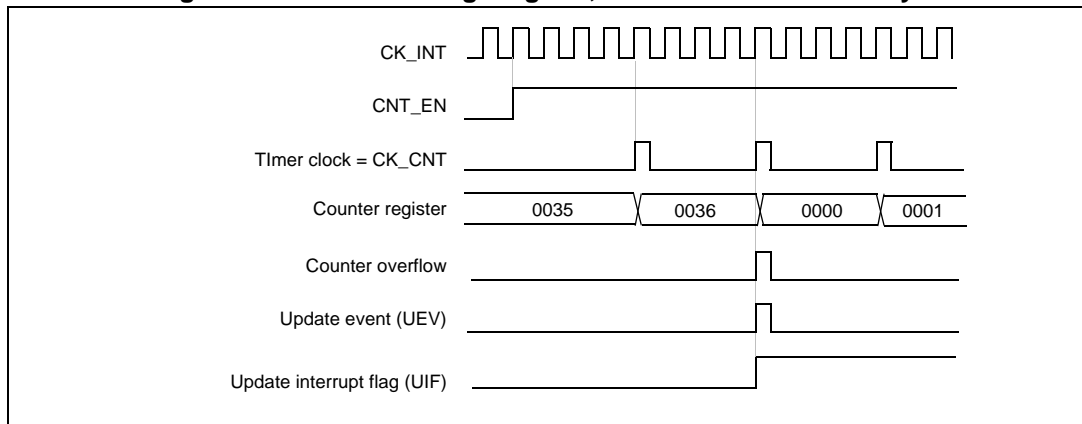
**Figure 90. Counter timing diagram, internal clock divided by 1**



**Figure 91. Counter timing diagram, internal clock divided by 2**

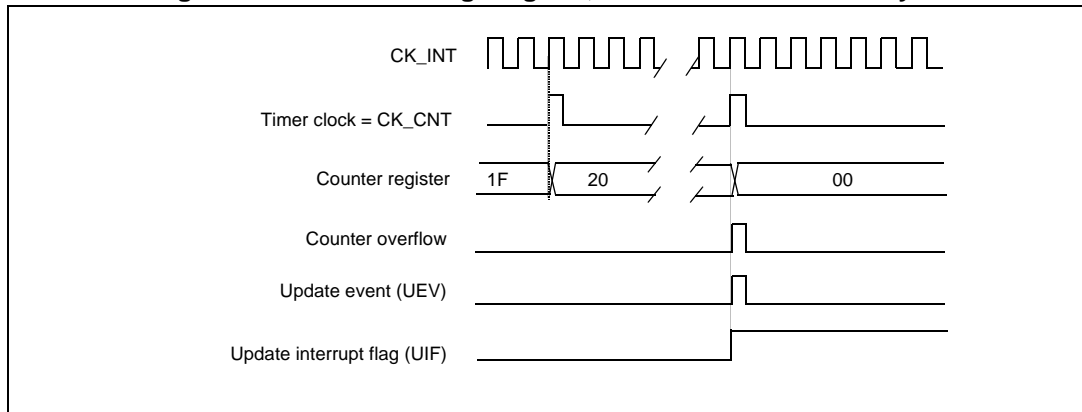


**Figure 92. Counter timing diagram, internal clock divided by 4**

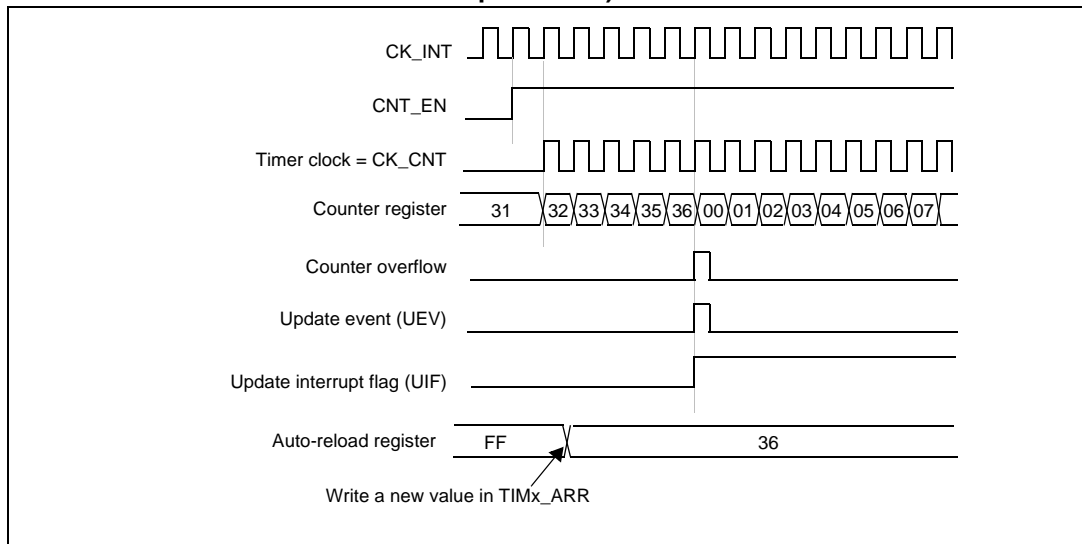




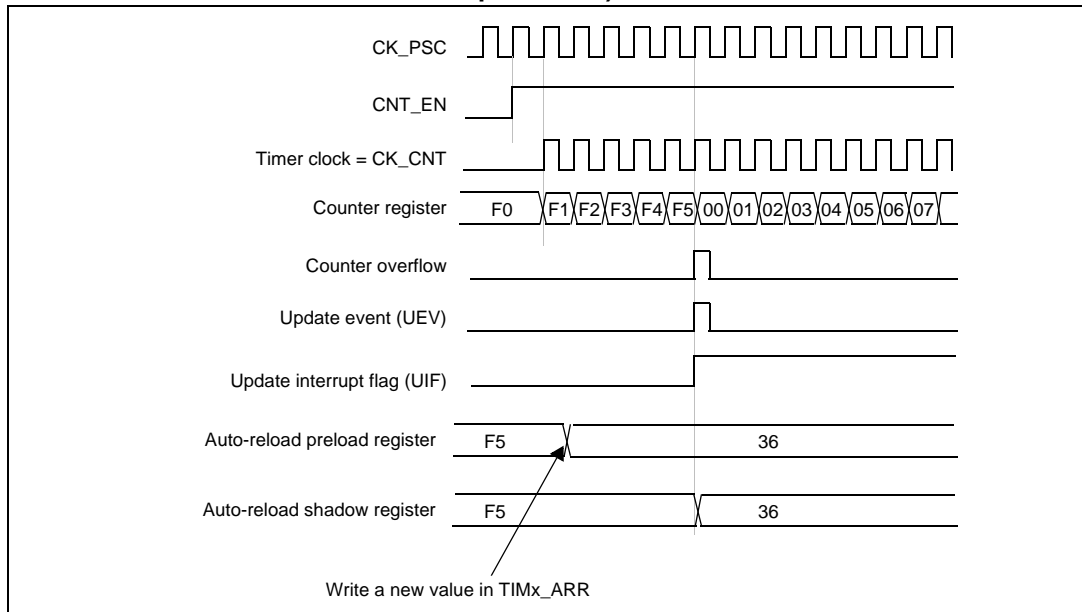
**Figure 93. Counter timing diagram, internal clock divided by N**



**Figure 94. Counter timing diagram, Update event when ARPE=0 (TIMx\_ARR not preloaded)**



**Figure 95. Counter timing diagram, Update event when ARPE=1 (TIMx\_ARR preloaded)**



**Downcounting mode**

In downcounting mode, the counter counts from the auto-reload value (content of the TIMx\_ARR register) down to 0, then restarts from the auto-reload value and generates a counter underflow event.

An Update event can be generate at each counter underflow or by setting the UG bit in the TIMx\_EGR register (by software or by using the slave mode controller)

The UEV update event can be disabled by software by setting the UDIS bit in TIMx\_CR1 register. This is to avoid updating the shadow registers while writing new values in the preload registers. Then no update event occurs until UDIS bit has been written to 0. However, the counter restarts from the current auto-reload value, whereas the counter of the prescaler restarts from 0 (but the prescale rate doesn't change).

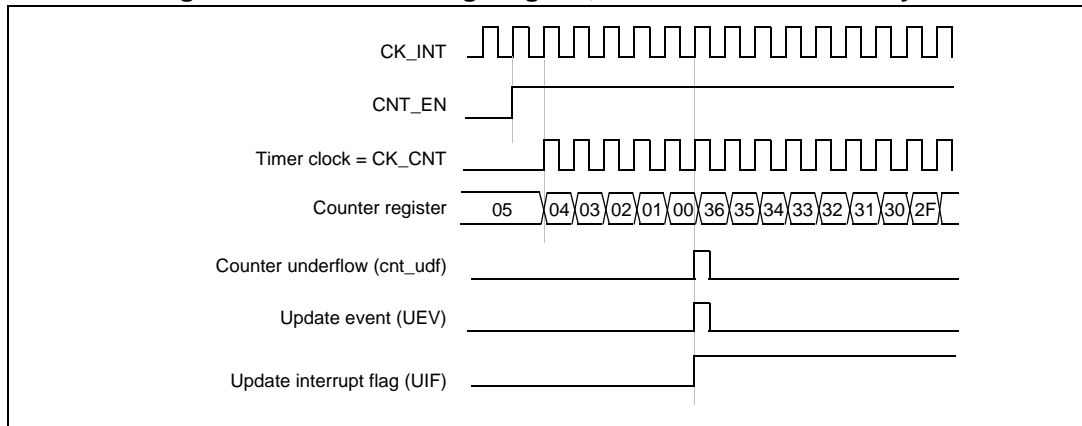
In addition, if the URS bit (update request selection) in TIMx\_CR1 register is set, setting the UG bit generates an update event UEV but without setting the UIF flag (thus no interrupt or DMA request is sent). This is to avoid generating both update and capture interrupts when clearing the counter on the capture event.

When an update event occurs, all the registers are updated and the update flag (UIF bit in TIMx\_SR register) is set (depending on the URS bit):

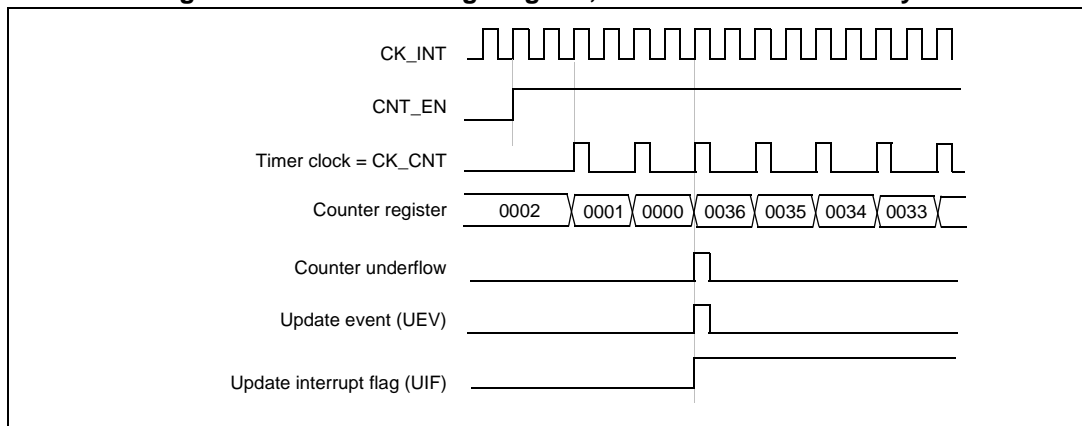
- The buffer of the prescaler is reloaded with the preload value (content of the TIMx\_PSC register).
- The auto-reload active register is updated with the preload value (content of the TIMx\_ARR register). Note that the auto-reload is updated before the counter is reloaded, so that the next period is the expected one.

The following figures show some examples of the counter behavior for different clock frequencies when TIMx\_ARR=0x36.

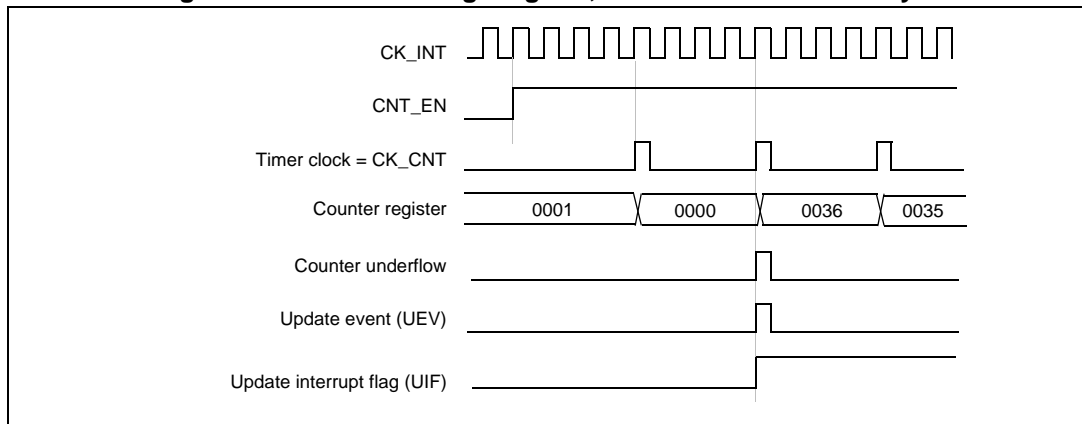
**Figure 96. Counter timing diagram, internal clock divided by 1**



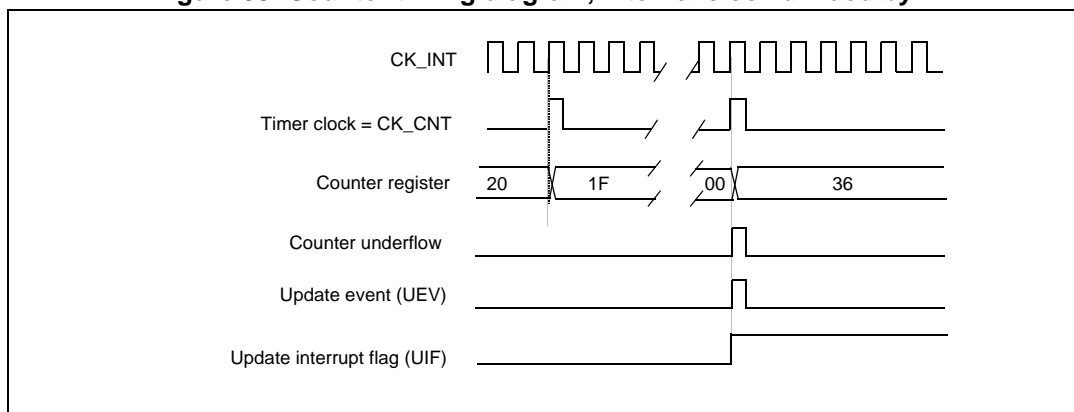
**Figure 97. Counter timing diagram, internal clock divided by 2**



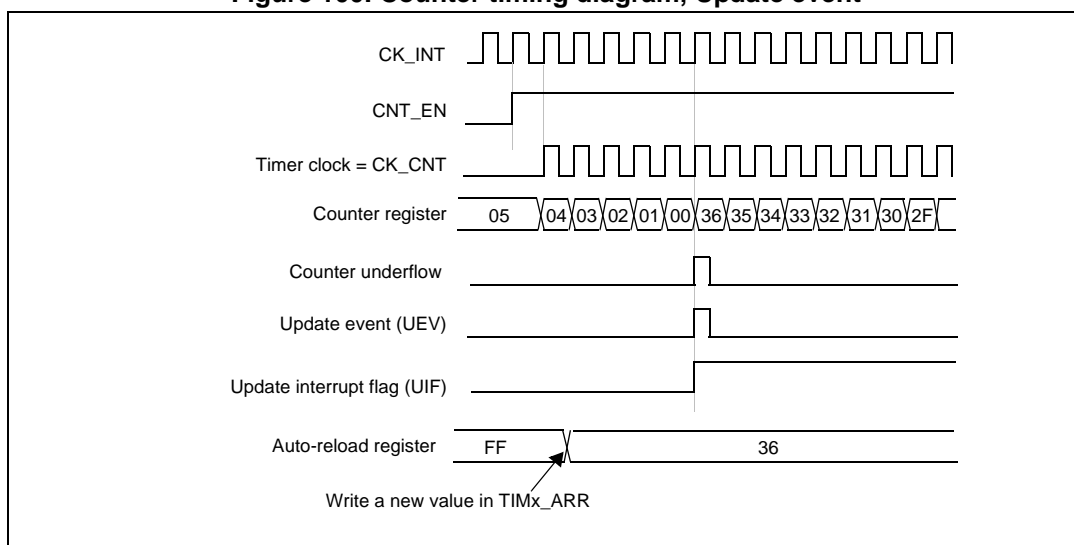
**Figure 98. Counter timing diagram, internal clock divided by 4**



**Figure 99. Counter timing diagram, internal clock divided by N**



**Figure 100. Counter timing diagram, Update event**



**Center-aligned mode (up/down counting)**

In center-aligned mode, the counter counts from 0 to the auto-reload value (content of the TIMx\_ARR register) – 1, generates a counter overflow event, then counts from the auto-reload value down to 1 and generates a counter underflow event. Then it restarts counting from 0.

Center-aligned mode is active when the CMS bits in TIMx\_CR1 register are not equal to '00'. The Output compare interrupt flag of channels configured in output is set when: the counter counts down (Center aligned mode 1, CMS = "01"), the counter counts up (Center aligned mode 2, CMS = "10") the counter counts up and down (Center aligned mode 3, CMS = "11").

In this mode, the direction bit (DIR from TIMx\_CR1 register) cannot be written. It is updated by hardware and gives the current direction of the counter.

The update event can be generated at each counter overflow and at each counter underflow or by setting the UG bit in the TIMx\_EGR register (by software or by using the slave mode controller) also generates an update event. In this case, the counter restarts counting from 0, as well as the counter of the prescaler.

The UEV update event can be disabled by software by setting the UDIS bit in TIMx\_CR1 register. This is to avoid updating the shadow registers while writing new values in the preload registers. Then no update event occurs until the UDIS bit has been written to 0. However, the counter continues counting up and down, based on the current auto-reload value.

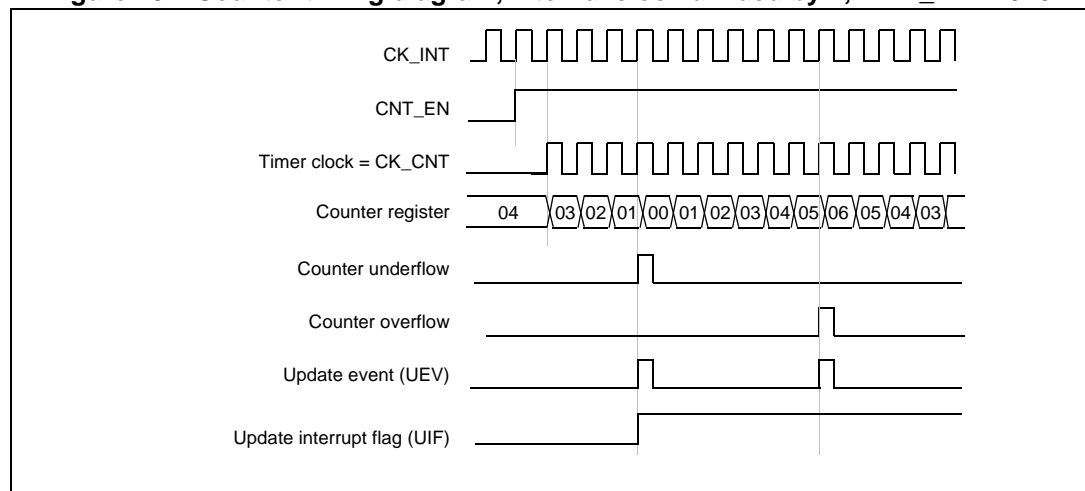
In addition, if the URS bit (update request selection) in TIMx\_CR1 register is set, setting the UG bit generates an update event UEV but without setting the UIF flag (thus no interrupt or DMA request is sent). This is to avoid generating both update and capture interrupt when clearing the counter on the capture event.

When an update event occurs, all the registers are updated and the update flag (UIF bit in TIMx\_SR register) is set (depending on the URS bit):

- The buffer of the prescaler is reloaded with the preload value (content of the TIMx\_PSC register).
- The auto-reload active register is updated with the preload value (content of the TIMx\_ARR register). Note that if the update source is a counter overflow, the auto-reload is updated before the counter is reloaded, so that the next period is the expected one (the counter is loaded with the new value).

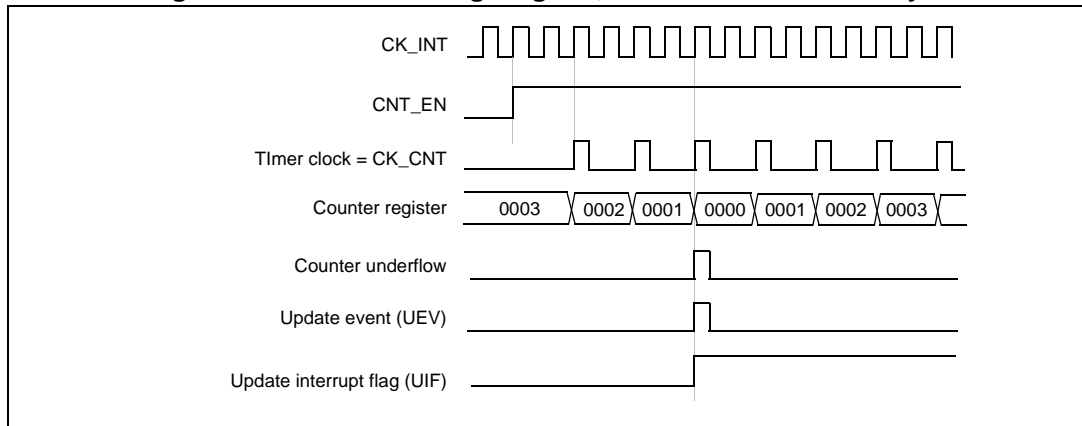
The following figures show some examples of the counter behavior for different clock frequencies.

**Figure 101. Counter timing diagram, internal clock divided by 1, TIMx\_ARR=0x6**

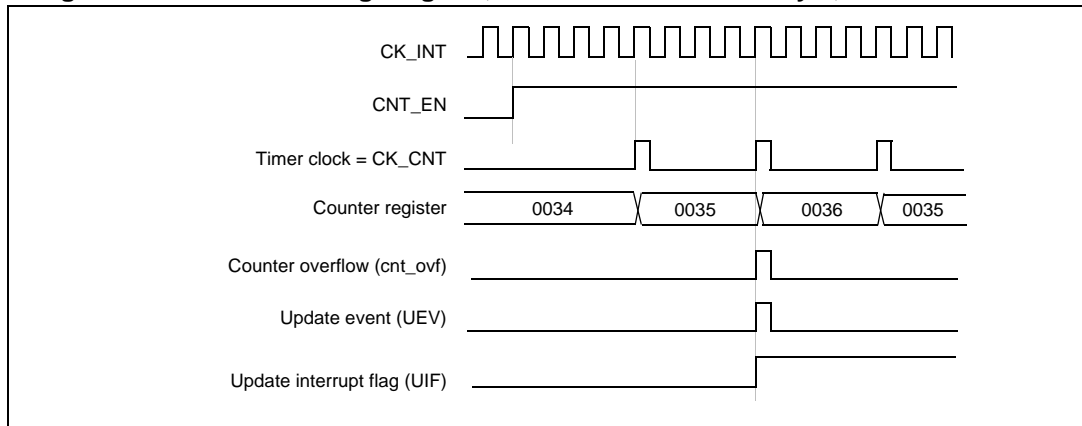


1. Here, center-aligned mode 1 is used (for more details refer to [Section 13.4.1: TIMx control register 1 \(TIMx\\_CR1\) on page 347](#)).

**Figure 102. Counter timing diagram, internal clock divided by 2**

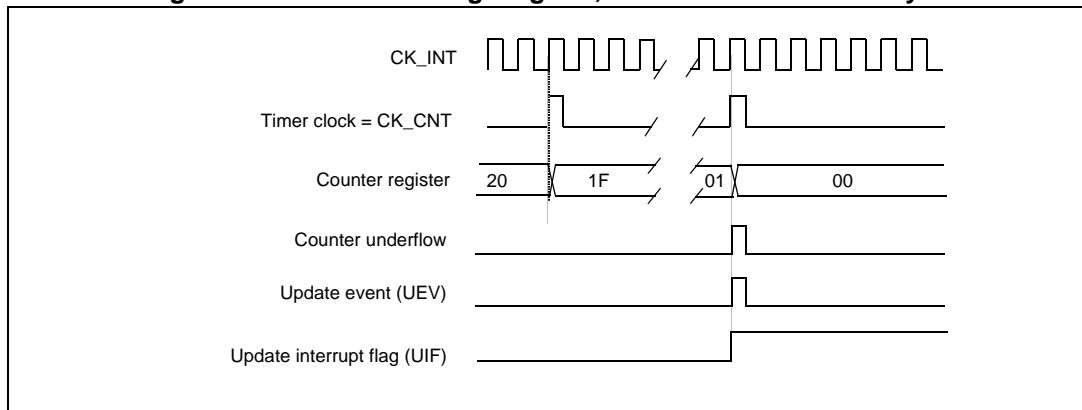


**Figure 103. Counter timing diagram, internal clock divided by 4, TIMx\_ARR=0x36**

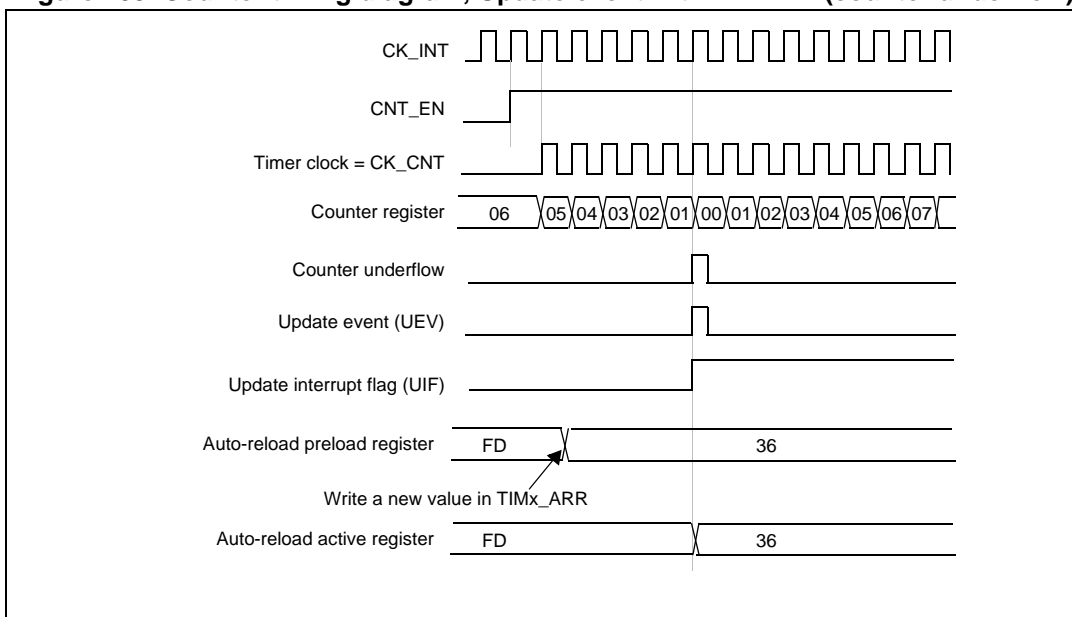


- Center-aligned mode 2 or 3 is used with an UIF on overflow.

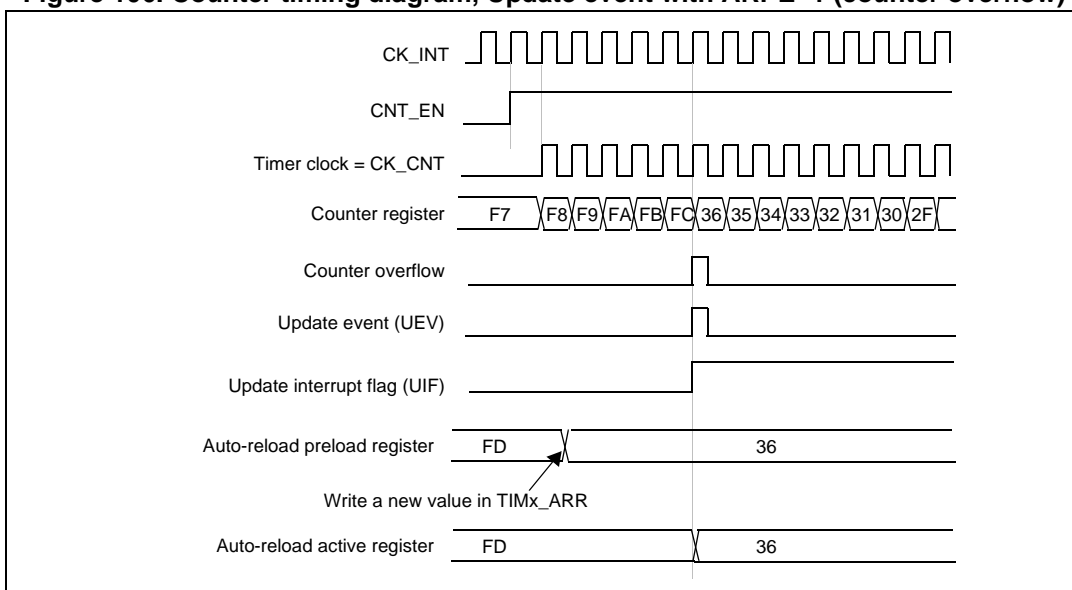
**Figure 104. Counter timing diagram, internal clock divided by N**



**Figure 105. Counter timing diagram, Update event with ARPE=1 (counter underflow)**



**Figure 106. Counter timing diagram, Update event with ARPE=1 (counter overflow)**



### 13.3.3 Clock selection

The counter clock can be provided by the following clock sources:

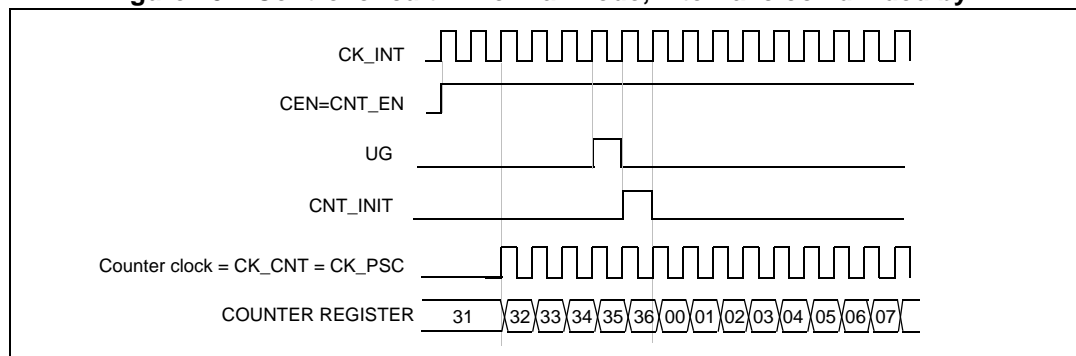
- Internal clock (CK\_INT)
- External clock mode1: external input pin (TIX)
- External clock mode2: external trigger input (ETR) available on TIM2, TIM3 and TIM4 only.
- Internal trigger inputs (ITRx): using one timer as prescaler for another timer, for example, you can configure Timer to act as a prescaler for Timer 2. Refer to : [Using one timer as prescaler for another timer on page 342](#) for more details.

### Internal clock source (CK\_INT)

If the slave mode controller is disabled (SMS=000 in the TIMx\_SMCR register), then the CEN, DIR (in the TIMx\_CR1 register) and UG bits (in the TIMx\_EGR register) are actual control bits and can be changed only by software (except UG which remains cleared automatically). As soon as the CEN bit is written to 1, the prescaler is clocked by the internal clock CK\_INT.

Figure 107 shows the behavior of the control circuit and the upcounter in normal mode, without prescaler.

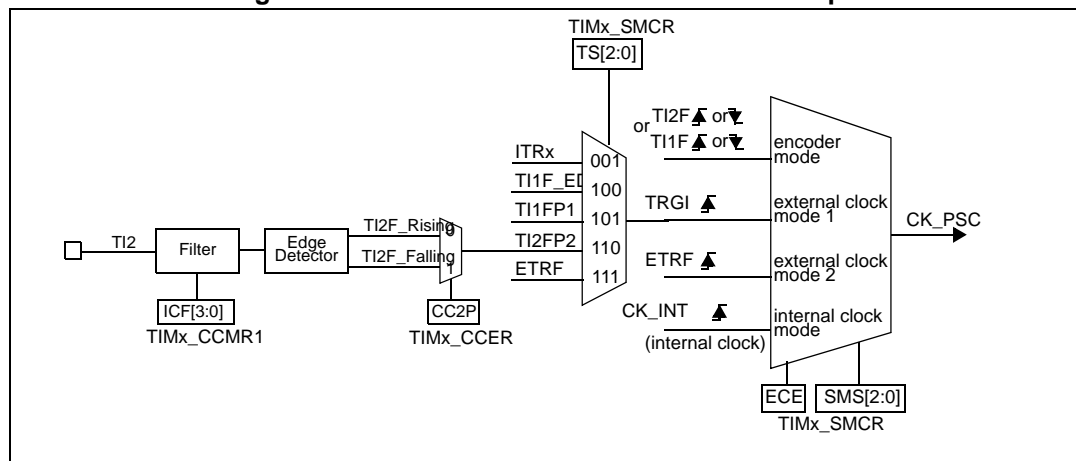
Figure 107. Control circuit in normal mode, internal clock divided by 1



### External clock source mode 1

This mode is selected when SMS=111 in the TIMx\_SMCR register. The counter can count at each rising or falling edge on a selected input.

Figure 108. TI2 external clock connection example



For example, to configure the upcounter to count in response to a rising edge on the TI2 input, use the following procedure:

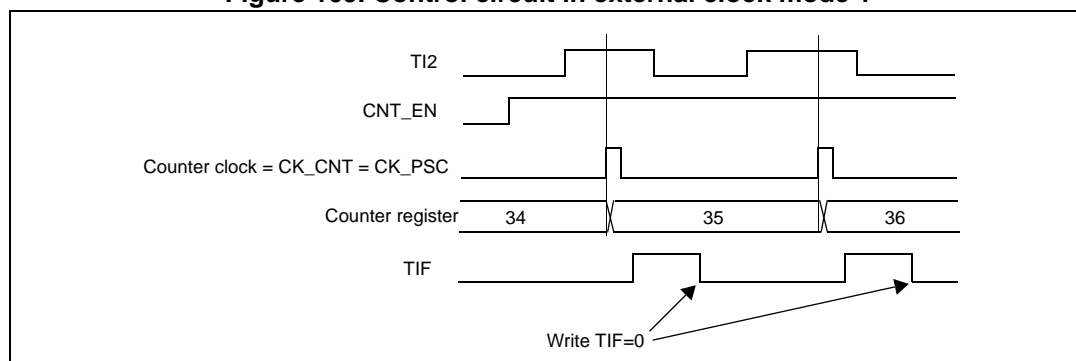
1. Configure channel 2 to detect rising edges on the TI2 input by writing CC2S= '01 in the TIMx\_CCMR1 register.
2. Configure the input filter duration by writing the IC2F[3:0] bits in the TIMx\_CCMR1 register (if no filter is needed, keep IC2F=0000).



- Note: The capture prescaler is not used for triggering, so you don't need to configure it.
3. Select rising edge polarity by writing CC2P=0 and CC2NP=0 in the TIMx\_CCER register.
  4. Configure the timer in external clock mode 1 by writing SMS=111 in the TIMx\_SMCR register.
  5. Select TI2 as the input source by writing TS=110 in the TIMx\_SMCR register.
  6. Enable the counter by writing CEN=1 in the TIMx\_CR1 register.

When a rising edge occurs on TI2, the counter counts once and the TIF flag is set.  
 The delay between the rising edge on TI2 and the actual clock of the counter is due to the resynchronization circuit on TI2 input.

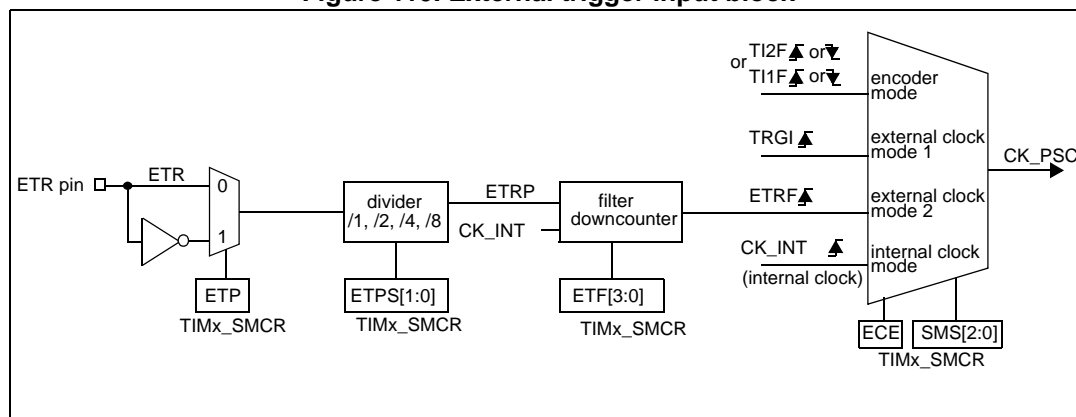
**Figure 109. Control circuit in external clock mode 1**



**External clock source mode 2**

This mode is selected by writing ECE=1 in the TIMx\_SMCR register.  
 The counter can count at each rising or falling edge on the external trigger input ETR.  
 Figure 110 gives an overview of the external trigger input block.

**Figure 110. External trigger input block**



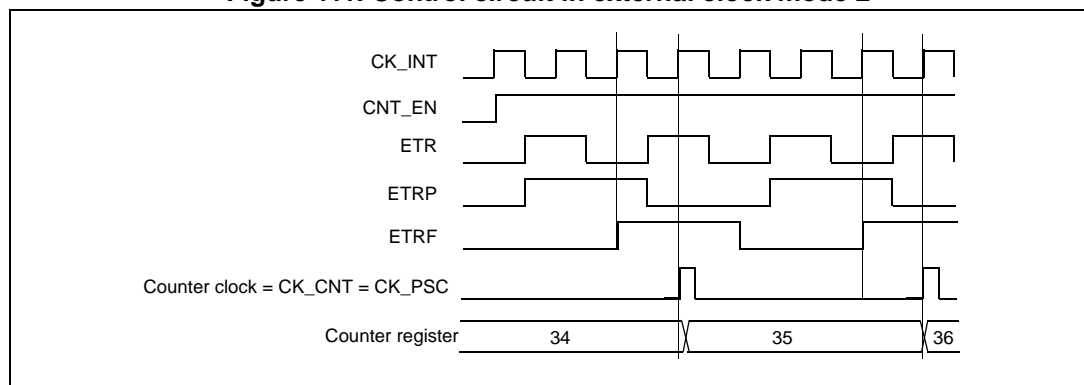
For example, to configure the upcounter to count each 2 rising edges on ETR, use the following procedure:

1. As no filter is needed in this example, write ETF[3:0]=0000 in the TIMx\_SMCR register.
2. Set the prescaler by writing ETPS[1:0]=01 in the TIMx\_SMCR register
3. Select rising edge detection on the ETR pin by writing ETP=0 in the TIMx\_SMCR register
4. Enable external clock mode 2 by writing ECE=1 in the TIMx\_SMCR register.
5. Enable the counter by writing CEN=1 in the TIMx\_CR1 register.

The counter counts once each 2 ETR rising edges.

The delay between the rising edge on ETR and the actual clock of the counter is due to the resynchronization circuit on the ETRP signal.

**Figure 111. Control circuit in external clock mode 2**



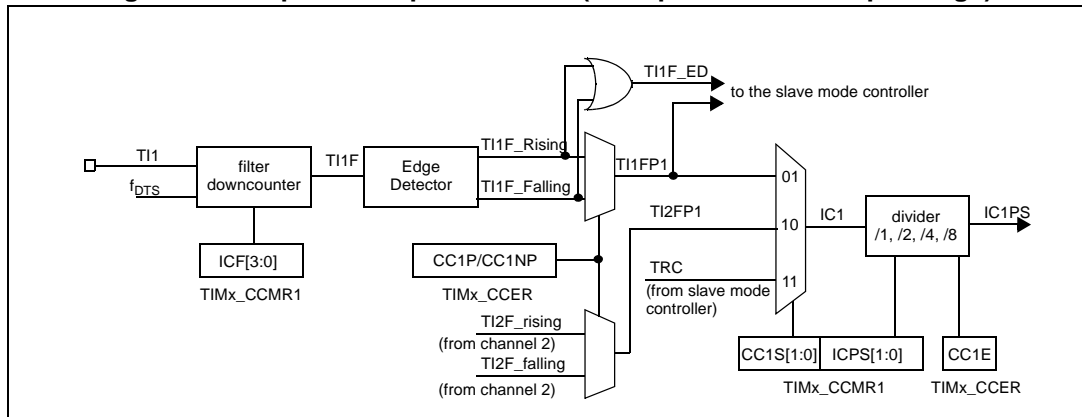
### 13.3.4 Capture/compare channels

Each Capture/Compare channel is built around a capture/compare register (including a shadow register), a input stage for capture (with digital filter, multiplexing and prescaler) and an output stage (with comparator and output control).

The following figure gives an overview of one Capture/Compare channel.

The input stage samples the corresponding Tlx input to generate a filtered signal TlxF. Then, an edge detector with polarity selection generates a signal (TlxFPx) which can be used as trigger input by the slave mode controller or as the capture command. It is prescaled before the capture register (ICxPS).

Figure 112. Capture/compare channel (example: channel 1 input stage)



The output stage generates an intermediate waveform which is then used for reference: OCxRef (active high). The polarity acts at the end of the chain.

Figure 113. Capture/compare channel 1 main circuit

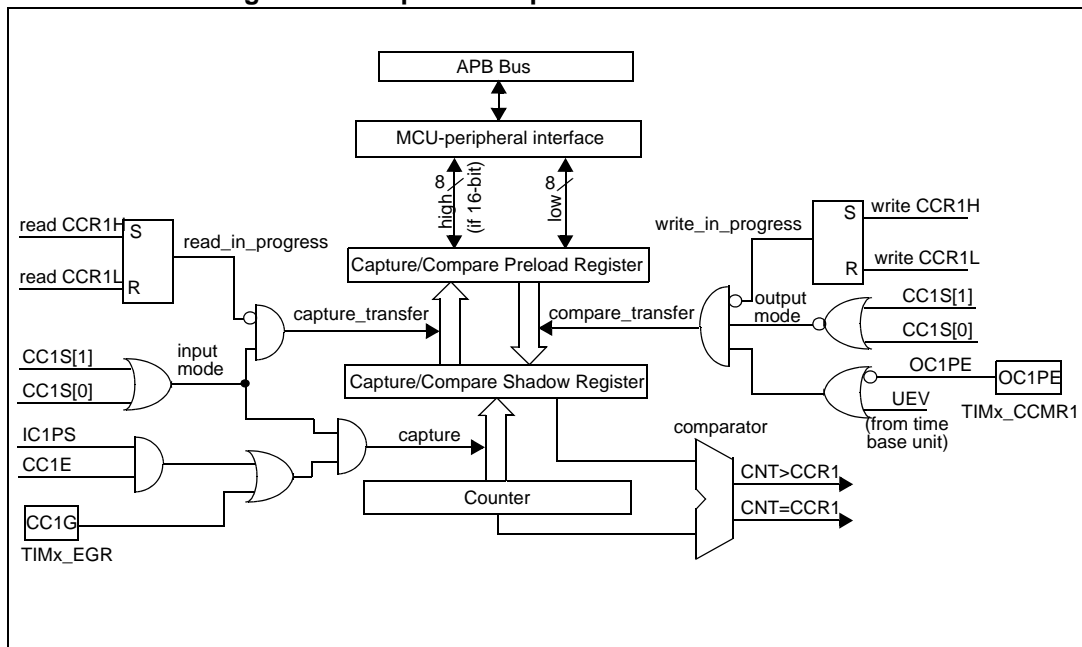
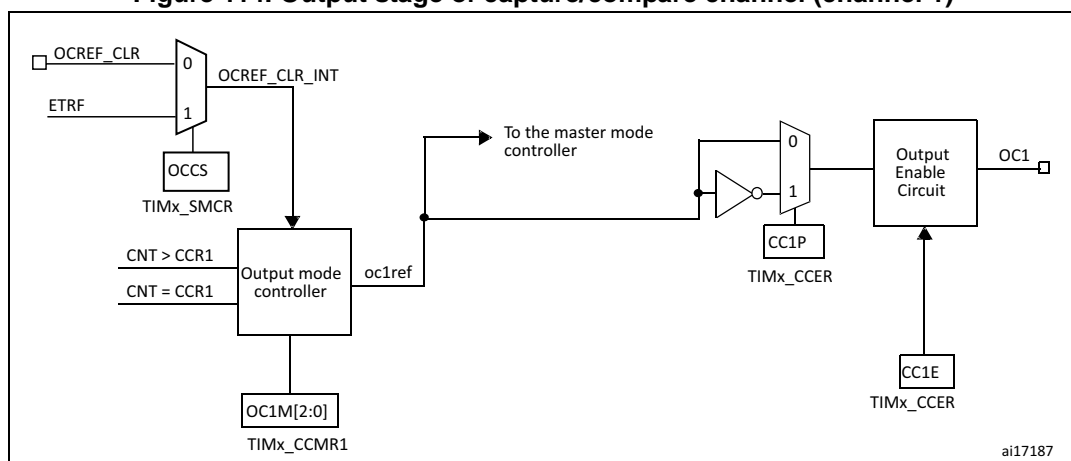


Figure 114. Output stage of capture/compare channel (channel 1)



The capture/compare block is made of one preload register and one shadow register. Write and read always access the preload register.

In capture mode, captures are actually done in the shadow register, which is copied into the preload register.

In compare mode, the content of the preload register is copied into the shadow register which is compared to the counter.

### 13.3.5 Input capture mode

In Input capture mode, the Capture/Compare Registers (TIMx\_CCRx) are used to latch the value of the counter after a transition detected by the corresponding ICx signal. When a capture occurs, the corresponding CCXIF flag (TIMx\_SR register) is set and an interrupt or a DMA request can be sent if they are enabled. If a capture occurs while the CCxIF flag was already high, then the over-capture flag CCxOF (TIMx\_SR register) is set. CCxIF can be cleared by software by writing it to 0 or by reading the captured data stored in the TIMx\_CCRx register. CCxOF is cleared when you write it to 0.

The following example shows how to capture the counter value in TIMx\_CCR1 when TI1 input rises. To do this, use the following procedure:

- Select the active input: TIMx\_CCR1 must be linked to the TI1 input, so write the CC1S bits to 01 in the TIMx\_CCMR1 register. As soon as CC1S becomes different from 00, the channel is configured in input and the TIMx\_CCR1 register becomes read-only.
- Program the input filter duration you need with respect to the signal you connect to the timer (by programming the ICxF bits in the TIMx\_CCMRx register if the input is one of the TIx inputs). Let's imagine that, when toggling, the input signal is not stable during at most 5 internal clock cycles. We must program a filter duration longer than these 5 clock cycles. We can validate a transition on TI1 when 8 consecutive samples with the

new level have been detected (sampled at  $f_{DTS}$  frequency). Then write IC1F bits to 0011 in the TIMx\_CCMR1 register.

- Select the edge of the active transition on the TI1 channel by writing the CC1P and CC1NP bits to 00 in the TIMx\_CCER register (rising edge in this case).
- Program the input prescaler. In our example, we wish the capture to be performed at each valid transition, so the prescaler is disabled (write IC1PS bits to 00 in the TIMx\_CCMR1 register).
- Enable capture from the counter into the capture register by setting the CC1E bit in the TIMx\_CCER register.
- If needed, enable the related interrupt request by setting the CC1IE bit in the TIMx\_DIER register, and/or the DMA request by setting the CC1DE bit in the TIMx\_DIER register.

When an input capture occurs:

- The TIMx\_CCR1 register gets the value of the counter on the active transition.
- CC1IF flag is set (interrupt flag). CC1OF is also set if at least two consecutive captures occurred whereas the flag was not cleared.
- An interrupt is generated depending on the CC1IE bit.
- A DMA request is generated depending on the CC1DE bit.

In order to handle the overcapture, it is recommended to read the data before the overcapture flag. This is to avoid missing an overcapture which could happen after reading the flag and before reading the data.

*Note:* IC interrupt and/or DMA requests can be generated by software by setting the corresponding CCxG bit in the TIMx\_EGR register.

### 13.3.6 PWM input mode

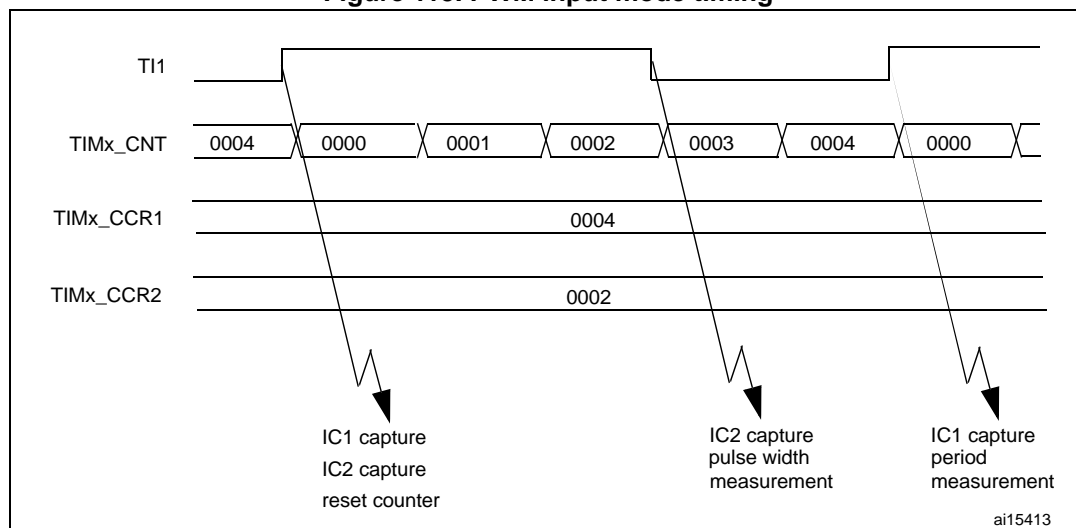
This mode is a particular case of input capture mode. The procedure is the same except:

- Two ICx signals are mapped on the same TIx input.
- These 2 ICx signals are active on edges with opposite polarity.
- One of the two TIxFP signals is selected as trigger input and the slave mode controller is configured in reset mode.

For example, you can measure the period (in TIMx\_CCR1 register) and the duty cycle (in TIMx\_CCR2 register) of the PWM applied on TI1 using the following procedure (depending on CK\_INT frequency and prescaler value):

- Select the active input for TIMx\_CCR1: write the CC1S bits to 01 in the TIMx\_CCMR1 register (TI1 selected).
- Select the active polarity for TI1FP1 (used both for capture in TIMx\_CCR1 and counter clear): write the CC1P to '0' and the CC1NP bit to '0' (active on rising edge).
- Select the active input for TIMx\_CCR2: write the CC2S bits to 10 in the TIMx\_CCMR1 register (TI1 selected).
- Select the active polarity for TI1FP2 (used for capture in TIMx\_CCR2): write the CC2P bit to '1' and the CC2NP bit to '0' (active on falling edge).
- Select the valid trigger input: write the TS bits to 101 in the TIMx\_SMCR register (TI1FP1 selected).
- Configure the slave mode controller in reset mode: write the SMS bits to 100 in the TIMx\_SMCR register.
- Enable the captures: write the CC1E and CC2E bits to '1' in the TIMx\_CCER register.

**Figure 115. PWM input mode timing**



### 13.3.7 Forced output mode

In output mode (CCxS bits = 00 in the TIMx\_CCMRx register), each output compare signal (OCxREF and then OCx) can be forced to active or inactive level directly by software, independently of any comparison between the output compare register and the counter.

To force an output compare signal (ocxref/OCx) to its active level, you just need to write 101 in the OCxM bits in the corresponding TIMx\_CCMRx register. Thus ocxref is forced high (OCxREF is always active high) and OCx get opposite value to CCxP polarity bit.

e.g.: CCxP=0 (OCx active high) => OCx is forced to high level.

ocxref signal can be forced low by writing the OCxM bits to 100 in the TIMx\_CCMRx register.

Anyway, the comparison between the TIMx\_CCRx shadow register and the counter is still performed and allows the flag to be set. Interrupt and DMA requests can be sent accordingly. This is described in the Output Compare Mode section.

### 13.3.8 Output compare mode

This function is used to control an output waveform or indicating when a period of time has elapsed.

When a match is found between the capture/compare register and the counter, the output compare function:

- Assigns the corresponding output pin to a programmable value defined by the output compare mode (OCxM bits in the TIMx\_CCMRx register) and the output polarity (CCxP bit in the TIMx\_CCER register). The output pin can keep its level (OCxM=000), be set active (OCxM=001), be set inactive (OCxM=010) or can toggle (OCxM=011) on match.
- Sets a flag in the interrupt status register (CCxIF bit in the TIMx\_SR register).
- Generates an interrupt if the corresponding interrupt mask is set (CCxIE bit in the TIMx\_DIER register).
- Sends a DMA request if the corresponding enable bit is set (CCxDE bit in the TIMx\_DIER register, CCDS bit in the TIMx\_CR2 register for the DMA request selection).

The TIMx\_CCRx registers can be programmed with or without preload registers using the OCxPE bit in the TIMx\_CCMRx register.

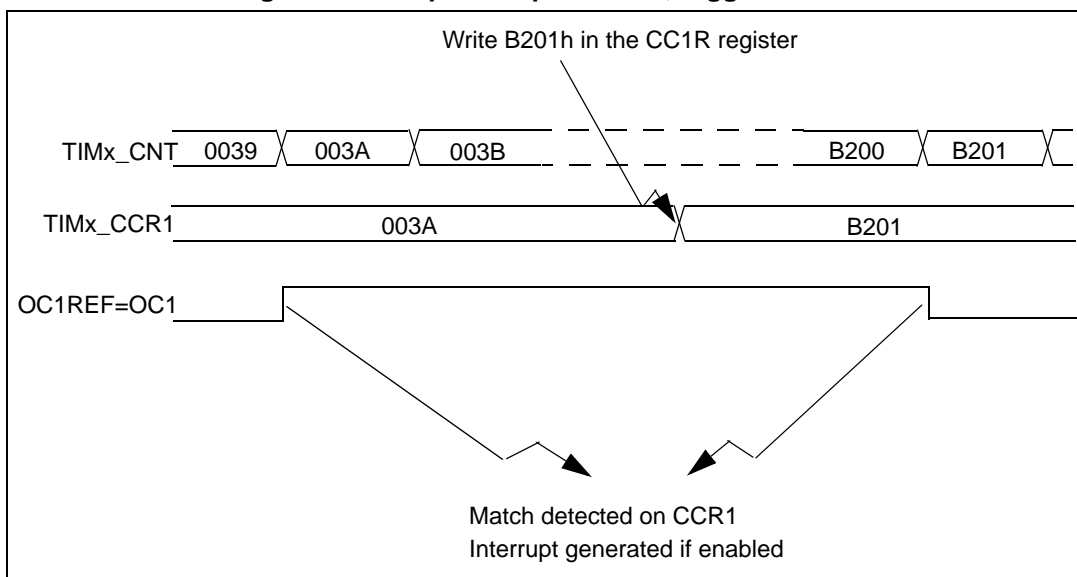
In output compare mode, the update event UEV has no effect on ocxref and OCx output. The timing resolution is one count of the counter. Output compare mode can also be used to output a single pulse (in One-pulse mode).

Procedure:

1. Select the counter clock (internal, external, prescaler).
2. Write the desired data in the TIMx\_ARR and TIMx\_CCRx registers.
3. Set the CCxIE and/or CCxDE bits if an interrupt and/or a DMA request is to be generated.
4. Select the output mode. For example, you must write OCxM=011, OCxPE=0, CCxP=0 and CCxE=1 to toggle OCx output pin when CNT matches CCRx, CCRx preload is not used, OCx is enabled and active high.
5. Enable the counter by setting the CEN bit in the TIMx\_CR1 register.

The TIMx\_CCRx register can be updated at any time by software to control the output waveform, provided that the preload register is not enabled (OCxPE=0, else TIMx\_CCRx shadow register is updated only at the next update event UEV). An example is given in [Figure 116](#).

Figure 116. Output compare mode, toggle on OC1



### 13.3.9 PWM mode

Pulse width modulation mode allows you to generate a signal with a frequency determined by the value of the TIMx\_ARR register and a duty cycle determined by the value of the TIMx\_CCRx register.

The PWM mode can be selected independently on each channel (one PWM per OCx output) by writing 110 (PWM mode 1) or '111 (PWM mode 2) in the OCxM bits in the TIMx\_CCMRx register. You must enable the corresponding preload register by setting the OCxPE bit in the TIMx\_CCMRx register, and eventually the auto-reload preload register by setting the ARPE bit in the TIMx\_CR1 register.

As the preload registers are transferred to the shadow registers only when an update event occurs, before starting the counter, you have to initialize all the registers by setting the UG bit in the TIMx\_EGR register.

OCx polarity is software programmable using the CCxP bit in the TIMx\_CCER register. It can be programmed as active high or active low. OCx output is enabled by the CCxE bit in the TIMx\_CCER register. Refer to the TIMx\_CCERx register description for more details.

In PWM mode (1 or 2), TIMx\_CNT and TIMx\_CCRx are always compared to determine whether  $TIMx\_CCRx \leq TIMx\_CNT$  or  $TIMx\_CNT \leq TIMx\_CCRx$  (depending on the direction of the counter). However, to comply with the ETRF (OCREF can be cleared by an external event through the ETR signal until the next PWM period), the OCREF signal is asserted only:

- When the result of the comparison changes, or
- When the output compare mode (OCxM bits in TIMx\_CCMRx register) switches from the "frozen" configuration (no comparison, OCxM='000) to one of the PWM modes (OCxM='110 or '111).

This forces the PWM by software while the timer is running.

The timer is able to generate PWM in edge-aligned mode or center-aligned mode depending on the CMS bits in the TIMx\_CR1 register.



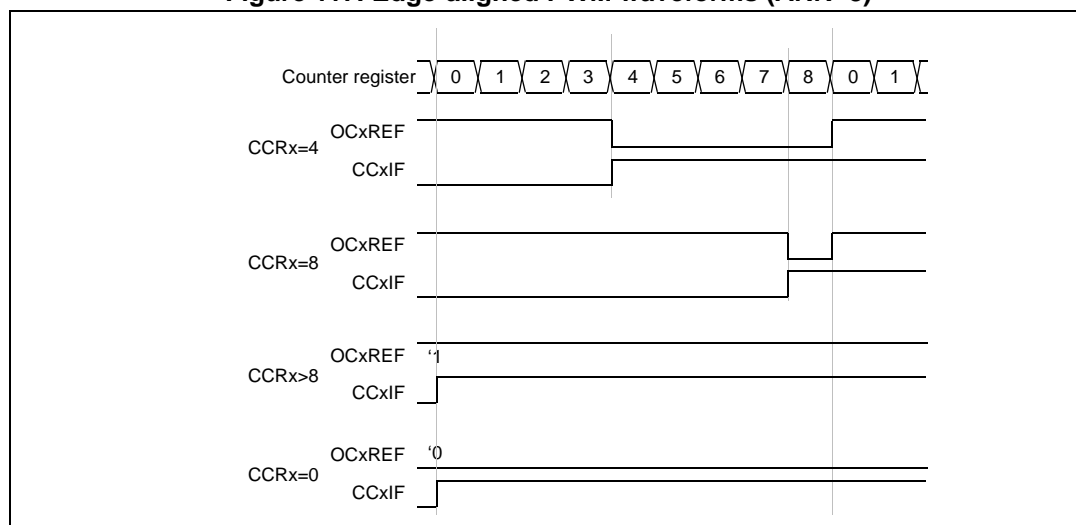
## PWM edge-aligned mode

### Upcounting configuration

Upcounting is active when the DIR bit in the TIMx\_CR1 register is low. Refer to [Section : Upcounting mode on page 314](#).

In the following example, we consider PWM mode 1. The reference PWM signal OCxREF is high as long as TIMx\_CNT <TIMx\_CCRx else it becomes low. If the compare value in TIMx\_CCRx is greater than the auto-reload value (in TIMx\_ARR) then OCxREF is held at '1. If the compare value is 0 then OCxREF is held at '0. [Figure 117](#) shows some edge-aligned PWM waveforms in an example where TIMx\_ARR=8.

**Figure 117. Edge-aligned PWM waveforms (ARR=8)**



### Downcounting configuration

Downcounting is active when DIR bit in TIMx\_CR1 register is high. Refer to [Section : Downcounting mode on page 317](#).

In PWM mode 1, the reference signal ocxref is low as long as TIMx\_CNT>TIMx\_CCRx else it becomes high. If the compare value in TIMx\_CCRx is greater than the auto-reload value in TIMx\_ARR, then ocxref is held at '1. 0% PWM is not possible in this mode.

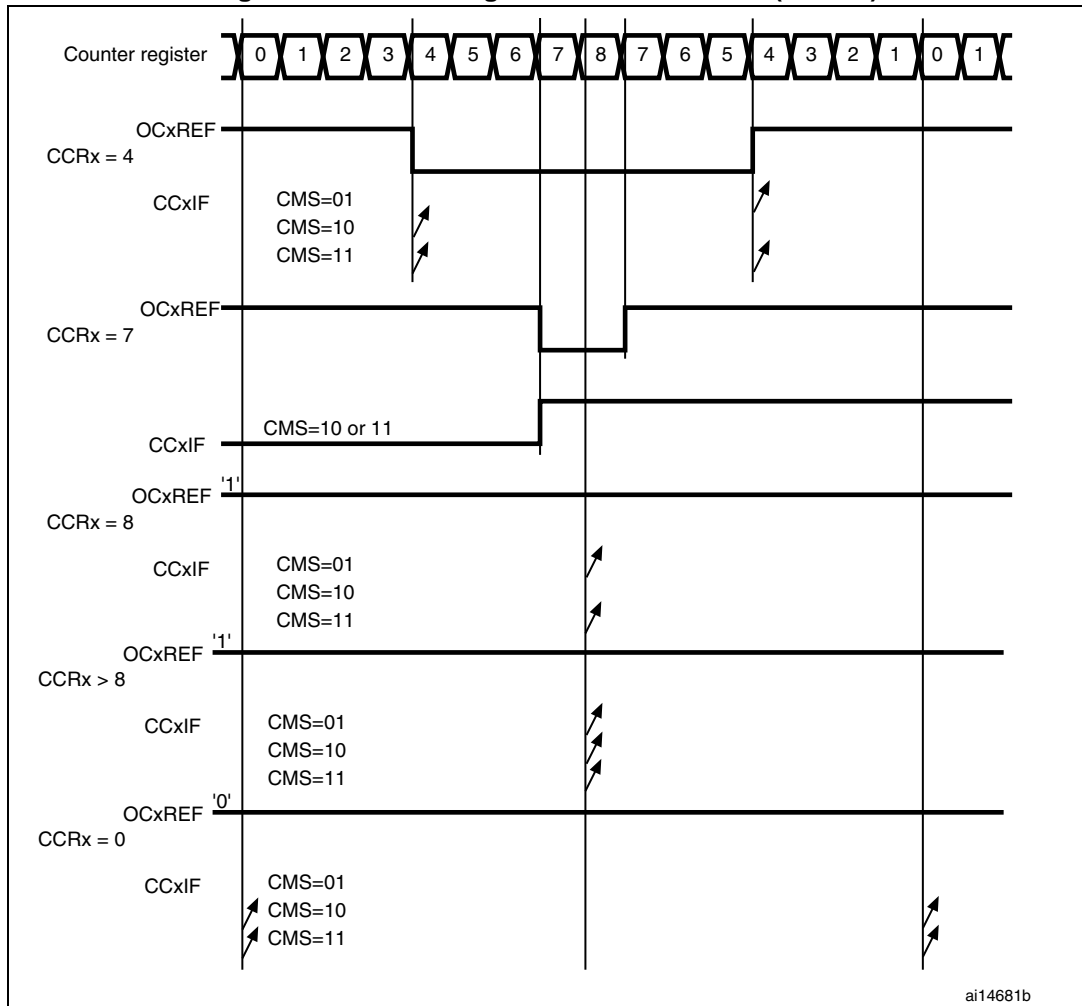
### PWM center-aligned mode

Center-aligned mode is active when the CMS bits in TIMx\_CR1 register are different from '00 (all the remaining configurations having the same effect on the ocxref/OCx signals). The compare flag is set when the counter counts up, when it counts down or both when it counts up and down depending on the CMS bits configuration. The direction bit (DIR) in the TIMx\_CR1 register is updated by hardware and must not be changed by software. Refer to [Section : Center-aligned mode \(up/down counting\) on page 319](#).

[Figure 118](#) shows some center-aligned PWM waveforms in an example where:

- TIMx\_ARR=8,
- PWM mode is the PWM mode 1,
- The flag is set when the counter counts down corresponding to the center-aligned mode 1 selected for CMS=01 in TIMx\_CR1 register.

Figure 118. Center-aligned PWM waveforms (ARR=8)



Hints on using center-aligned mode:

- When starting in center-aligned mode, the current up-down configuration is used. It means that the counter counts up or down depending on the value written in the DIR bit in the TIMx\_CR1 register. Moreover, the DIR and CMS bits must not be changed at the same time by the software.
- Writing to the counter while running in center-aligned mode is not recommended as it can lead to unexpected results. In particular:
  - The direction is not updated if you write a value in the counter that is greater than the auto-reload value (TIMx\_CNT > TIMx\_ARR). For example, if the counter was counting up, it continues to count up.
  - The direction is updated if you write 0 or write the TIMx\_ARR value in the counter but no Update Event UEV is generated.
- The safest way to use center-aligned mode is to generate an update by software (setting the UG bit in the TIMx\_EGR register) just before starting the counter and not to write the counter while it is running.

### 13.3.10 One-pulse mode

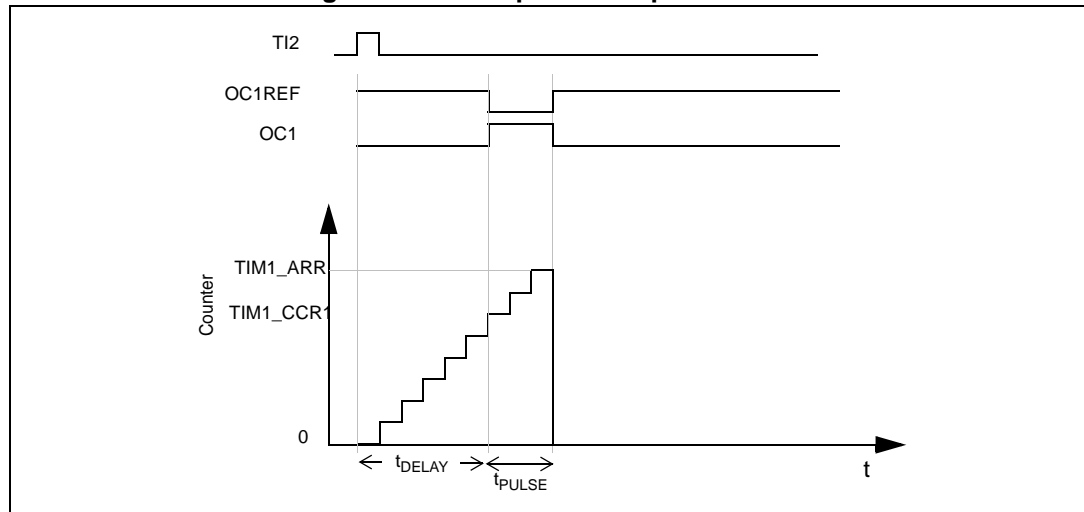
One-pulse mode (OPM) is a particular case of the previous modes. It allows the counter to be started in response to a stimulus and to generate a pulse with a programmable length after a programmable delay.

Starting the counter can be controlled through the slave mode controller. Generating the waveform can be done in output compare mode or PWM mode. You select One-pulse mode by setting the OPM bit in the TIMx\_CR1 register. This makes the counter stop automatically at the next update event UEV.

A pulse can be correctly generated only if the compare value is different from the counter initial value. Before starting (when the timer is waiting for the trigger), the configuration must be:

- In upcounting:  $CNT < CCRx \leq ARR$  (in particular,  $0 < CCRx$ ),
- In downcounting:  $CNT > CCRx$ .

Figure 119. Example of one-pulse mode



For example you may want to generate a positive pulse on OC1 with a length of  $t_{PULSE}$  and after a delay of  $t_{DELAY}$  as soon as a positive edge is detected on the TI2 input pin.

Let's use TI2FP2 as trigger 1:

- Map TI2FP2 on TI2 by writing  $CC2S=01$  in the TIMx\_CCMR1 register.
- TI2FP2 must detect a rising edge, write  $CC2P=0$  and  $CC2NP='0'$  in the TIMx\_CCER register.
- Configure TI2FP2 as trigger for the slave mode controller (TRGI) by writing  $TS=110$  in the TIMx\_SMCR register.
- TI2FP2 is used to start the counter by writing  $SMS$  to '110 in the TIMx\_SMCR register (trigger mode).

The OPM waveform is defined by writing the compare registers (taking into account the clock frequency and the counter prescaler).

- The  $t_{\text{DELAY}}$  is defined by the value written in the TIMx\_CCR1 register.
- The  $t_{\text{PULSE}}$  is defined by the difference between the auto-reload value and the compare value (TIMx\_ARR - TIMx\_CCR + 1).
- Let's say you want to build a waveform with a transition from '0 to '1 when a compare match occurs and a transition from '1 to '0 when the counter reaches the auto-reload value. To do this you enable PWM mode 2 by writing OC1M=111 in the TIMx\_CCMR1 register. You can optionally enable the preload registers by writing OC1PE=1 in the TIMx\_CCMR1 register and ARPE in the TIMx\_CR1 register. In this case you have to write the compare value in the TIMx\_CCR1 register, the auto-reload value in the TIMx\_ARR register, generate an update by setting the UG bit and wait for external trigger event on TI2. CC1P is written to '0 in this example.

In our example, the DIR and CMS bits in the TIMx\_CR1 register should be low.

You only want 1 pulse (Single mode), so you write '1 in the OPM bit in the TIMx\_CR1 register to stop the counter at the next update event (when the counter rolls over from the auto-reload value back to 0). When OPM bit in the TIMx\_CR1 register is set to '0', so the Repetitive Mode is selected.

#### Particular case: OCx fast enable:

In One-pulse mode, the edge detection on Tlx input set the CEN bit which enables the counter. Then the comparison between the counter and the compare value makes the output toggle. But several clock cycles are needed for these operations and it limits the minimum delay  $t_{\text{DELAY min}}$  we can get.

If you want to output a waveform with the minimum delay, you can set the OCxFE bit in the TIMx\_CCMRx register. Then OCxRef (and OCx) is forced in response to the stimulus, without taking in account the comparison. Its new level is the same as if a compare match had occurred. OCxFE acts only if the channel is configured in PWM1 or PWM2 mode.

### 13.3.11 Clearing the OCxREF signal on an external event

The OCxREF signal for a given channel can be driven Low by applying a High level to the ETRF input (OCxCE enable bit of the corresponding TIMx\_CCMRx register set to '1'). The OCxREF signal remains Low until the next update event, UEV, occurs.

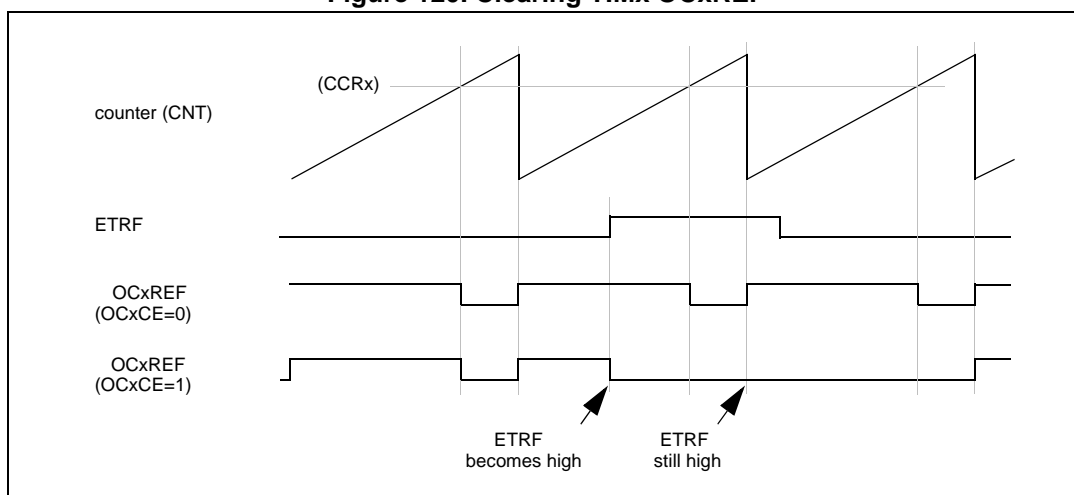
This function can only be used in output compare and PWM modes, and does not work in forced mode.

For example, the ETR signal can be connected to the output of a comparator to be used for current handling. In this case, ETR must be configured as follows:

1. The external trigger prescaler should be kept off: bits ETPS[1:0] in the TIMx\_SMCR register are cleared to 00.
2. The external clock mode 2 must be disabled: bit ECE in the TIM1\_SMCR register is cleared to 0.
3. The external trigger polarity (ETP) and the external trigger filter (ETF) can be configured according to the application's needs.

*Figure 120* shows the behavior of the OCxREF signal when the ETRF input becomes high, for both values of the OCxCE enable bit. In this example, the timer TIMx is programmed in PWM mode.

Figure 120. Clearing TIMx OCxREF



1. In case of a PWM with a 100% duty cycle (if  $CCR_x > ARR$ ), OCxREF is enabled again at the next counter overflow.

### 13.3.12 Encoder interface mode

To select Encoder Interface mode write  $SMS=001$  in the TIMx\_SMCR register if the counter is counting on TI2 edges only,  $SMS=010$  if it is counting on TI1 edges only and  $SMS=011$  if it is counting on both TI1 and TI2 edges.

Select the TI1 and TI2 polarity by programming the CC1P and CC2P bits in the TIMx\_CCER register. When needed, you can program the input filter as well.

The two inputs TI1 and TI2 are used to interface to an incremental encoder. Refer to [Table 53](#). The counter is clocked by each valid transition on TI1FP1 or TI2FP2 (TI1 and TI2 after input filter and polarity selection, TI1FP1=TI1 if not filtered and not inverted, TI2FP2=TI2 if not filtered and not inverted) assuming that it is enabled (CEN bit in TIMx\_CR1 register written to '1'). The sequence of transitions of the two inputs is evaluated and generates count pulses as well as the direction signal. Depending on the sequence the counter counts up or down, the DIR bit in the TIMx\_CR1 register is modified by hardware accordingly. The DIR bit is calculated at each transition on any input (TI1 or TI2), whatever the counter is counting on TI1 only, TI2 only or both TI1 and TI2.

Encoder interface mode acts simply as an external clock with direction selection. This means that the counter just counts continuously between 0 and the auto-reload value in the TIMx\_ARR register (0 to ARR or ARR down to 0 depending on the direction). So you must configure TIMx\_ARR before starting. In the same way, the capture, compare, prescaler, trigger output features continue to work as normal.

In this mode, the counter is modified automatically following the speed and the direction of the incremental encoder and its content, therefore, always represents the encoder's position. The count direction correspond to the rotation direction of the connected sensor. The table summarizes the possible combinations, assuming TI1 and TI2 don't switch at the same time.

**Table 53. Counting direction versus encoder signals**

Active edge	Level on opposite signal (TI1FP1 for TI2, TI2FP2 for TI1)	TI1FP1 signal		TI2FP2 signal	
		Rising	Falling	Rising	Falling
Counting on TI1 only	High	Down	Up	No Count	No Count
	Low	Up	Down	No Count	No Count
Counting on TI2 only	High	No Count	No Count	Up	Down
	Low	No Count	No Count	Down	Up
Counting on TI1 and TI2	High	Down	Up	Up	Down
	Low	Up	Down	Down	Up

An external incremental encoder can be connected directly to the MCU without external interface logic. However, comparators are normally be used to convert the encoder’s differential outputs to digital signals. This greatly increases noise immunity. The third encoder output which indicate the mechanical zero position, may be connected to an external interrupt input and trigger a counter reset.

Figure 121 gives an example of counter operation, showing count signal generation and direction control. It also shows how input jitter is compensated where both edges are selected. This might occur if the sensor is positioned near to one of the switching points. For this example we assume that the configuration is the following:

- CC1S= ‘01’ (TIMx\_CCMR1 register, TI1FP1 mapped on TI1)
- CC2S= ‘01’ (TIMx\_CCMR2 register, TI2FP2 mapped on TI2)
- CC1P= ‘0’, CC1NP = ‘0’, IC1F =‘0000’ (TIMx\_CCER register, TI1FP1 noninverted, TI1FP1=TI1)
- CC2P= ‘0’, CC2NP = ‘0’, IC2F =‘0000’ (TIMx\_CCER register, TI2FP2 noninverted, TI2FP2=TI2)
- SMS= ‘011’ (TIMx\_SMCR register, both inputs are active on both rising and falling edges)
- CEN = 1 (TIMx\_CR1 register, Counter is enabled)

**Figure 121. Example of counter operation in encoder interface mode**

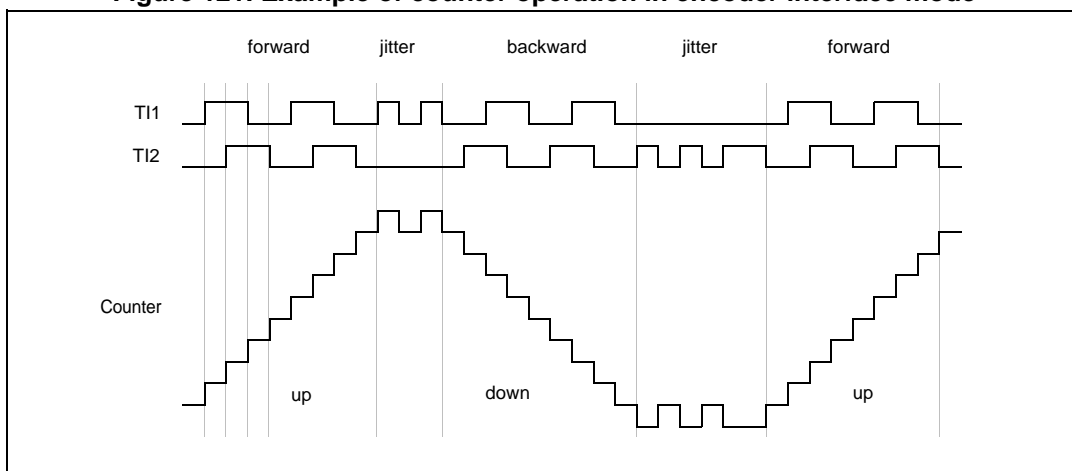
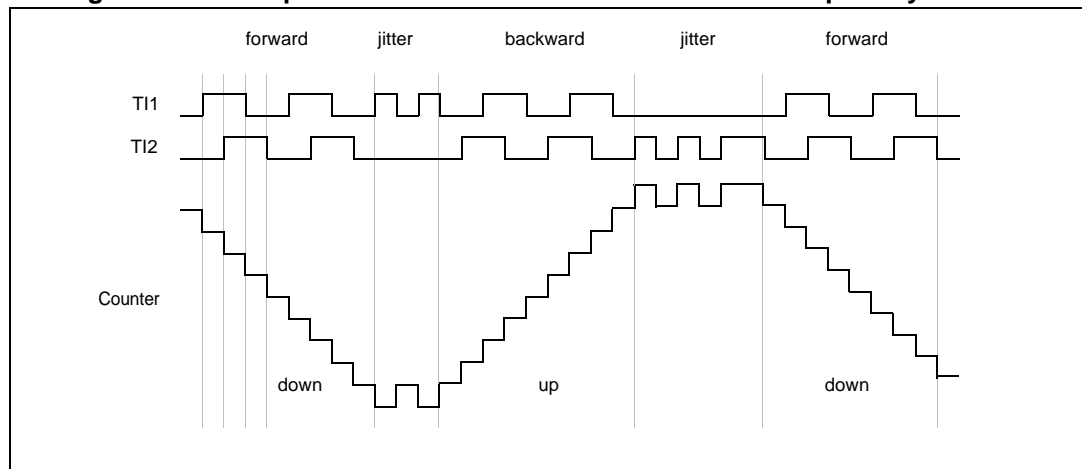


Figure 122 gives an example of counter behavior when TI1FP1 polarity is inverted (same configuration as above except CC1P=1).

**Figure 122. Example of encoder interface mode with TI1FP1 polarity inverted**



The timer, when configured in Encoder Interface mode provides information on the sensor's current position. You can obtain dynamic information (speed, acceleration, deceleration) by measuring the period between two encoder events using a second timer configured in capture mode. The output of the encoder which indicates the mechanical zero can be used for this purpose. Depending on the time between two events, the counter can also be read at regular times. You can do this by latching the counter value into a third input capture register if available (then the capture signal must be periodic and can be generated by another timer). when available, it is also possible to read its value through a DMA request generated by a Real-Time clock.

### 13.3.13 Timer input XOR function

The TI1S bit in the TIM\_CR2 register, allows the input filter of channel 1 to be connected to the output of a XOR gate, combining the three input pins TIMx\_CH1 to TIMx\_CH3.

The XOR output can be used with all the timer input functions such as trigger or input capture.

### 13.3.14 Timers and external trigger synchronization

The TIMx Timers can be synchronized with an external trigger in several modes: Reset mode, Gated mode and Trigger mode.

#### Slave mode: Reset mode

The counter and its prescaler can be reinitialized in response to an event on a trigger input. Moreover, if the URS bit from the TIMx\_CR1 register is low, an update event UEV is generated. Then all the preloaded registers (TIMx\_ARR, TIMx\_CCRx) are updated.

In the following example, the upcounter is cleared in response to a rising edge on TI1 input:

- Configure the channel 1 to detect rising edges on TI1. Configure the input filter duration (in this example, we don't need any filter, so we keep IC1F=0000). The capture prescaler is not used for triggering, so you don't need to configure it. The CC1S bits select the input capture source only, CC1S = 01 in the TIMx\_CCMR1 register. Write

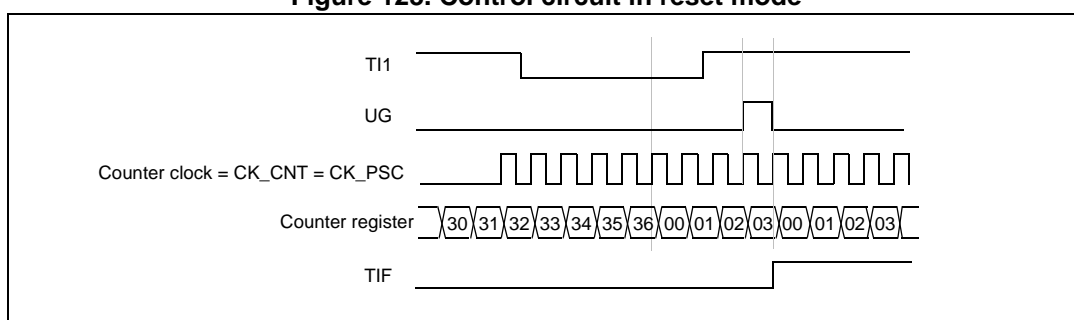
CC1P=0 and CC1NP=0 in TIMx\_CCER register to validate the polarity (and detect rising edges only).

- Configure the timer in reset mode by writing SMS=100 in TIMx\_SMCR register. Select TI1 as the input source by writing TS=101 in TIMx\_SMCR register.
- Start the counter by writing CEN=1 in the TIMx\_CR1 register.

The counter starts counting on the internal clock, then behaves normally until TI1 rising edge. When TI1 rises, the counter is cleared and restarts from 0. In the meantime, the trigger flag is set (TIF bit in the TIMx\_SR register) and an interrupt request, or a DMA request can be sent if enabled (depending on the TIE and TDE bits in TIMx\_DIER register).

The following figure shows this behavior when the auto-reload register TIMx\_ARR=0x36. The delay between the rising edge on TI1 and the actual reset of the counter is due to the resynchronization circuit on TI1 input.

**Figure 123. Control circuit in reset mode**



**Slave mode: Gated mode**

The counter can be enabled depending on the level of a selected input.

In the following example, the upcounter counts only when TI1 input is low:

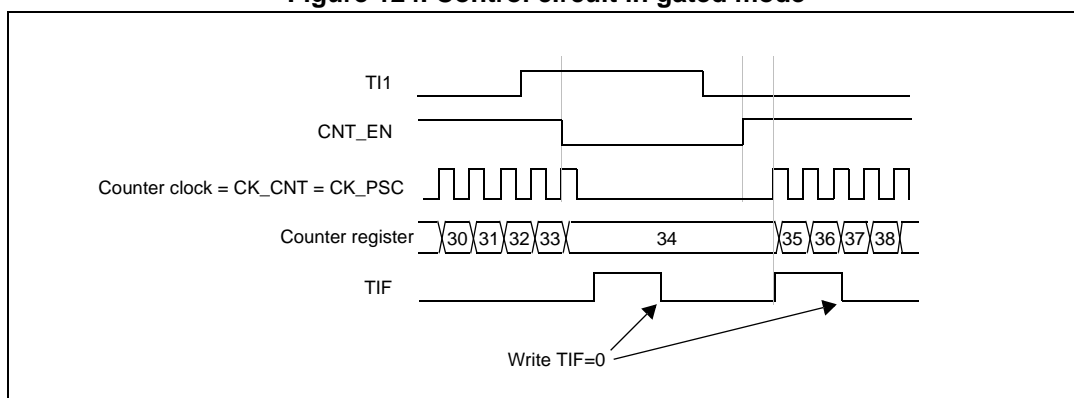
- Configure the channel 1 to detect low levels on TI1. Configure the input filter duration (in this example, we don't need any filter, so we keep IC1F=0000). The capture prescaler is not used for triggering, so you don't need to configure it. The CC1S bits select the input capture source only, CC1S=01 in TIMx\_CCMR1 register. Write CC1P=1 in TIMx\_CCER register to validate the polarity (and detect low level only).
- Configure the timer in gated mode by writing SMS=101 in TIMx\_SMCR register. Select TI1 as the input source by writing TS=101 in TIMx\_SMCR register.
- Enable the counter by writing CEN=1 in the TIMx\_CR1 register (in gated mode, the counter doesn't start if CEN=0, whatever is the trigger input level).

The counter starts counting on the internal clock as long as TI1 is low and stops as soon as TI1 becomes high. The TIF flag in the TIMx\_SR register is set both when the counter starts or stops.

The delay between the rising edge on TI1 and the actual stop of the counter is due to the resynchronization circuit on TI1 input.



**Figure 124. Control circuit in gated mode**



1. The configuration “CCxP=CCxNP=1” (detection of both rising and falling edges) does not have any effect in gated mode because gated mode acts on a level and not on an edge.

**Slave mode: Trigger mode**

The counter can start in response to an event on a selected input.

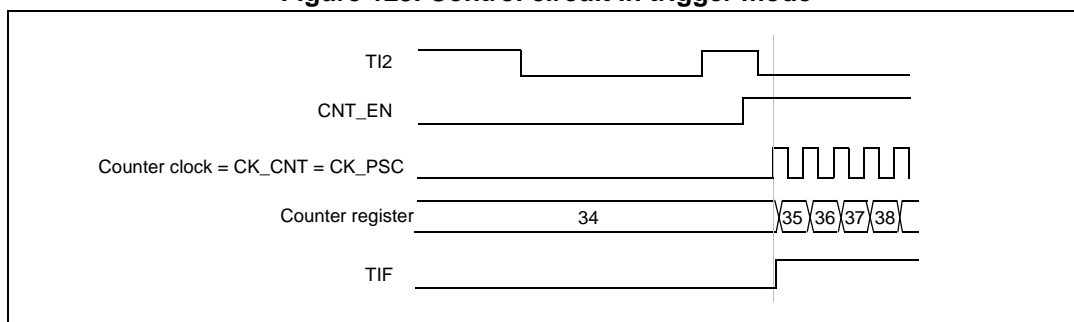
In the following example, the upcounter starts in response to a rising edge on TI2 input:

- Configure the channel 2 to detect rising edges on TI2. Configure the input filter duration (in this example, we don’t need any filter, so we keep IC2F=0000). The capture prescaler is not used for triggering, so you don’t need to configure it. CC2S bits are selecting the input capture source only, CC2S=01 in TIMx\_CCMR1 register. Write CC2P=1 in TIMx\_CCER register to validate the polarity (and detect low level only).
- Configure the timer in trigger mode by writing SMS=110 in TIMx\_SMCR register. Select TI2 as the input source by writing TS=110 in TIMx\_SMCR register.

When a rising edge occurs on TI2, the counter starts counting on the internal clock and the TIF flag is set.

The delay between the rising edge on TI2 and the actual start of the counter is due to the resynchronization circuit on TI2 input.

**Figure 125. Control circuit in trigger mode**



**Slave mode: External Clock mode 2 + trigger mode**

The external clock mode 2 can be used in addition to another slave mode (except external clock mode 1 and encoder mode). In this case, the ETR signal is used as external clock input, and another input can be selected as trigger input when operating in reset mode, gated mode or trigger mode. It is recommended not to select ETR as TRGI through the TS bits of TIMx\_SMCR register.

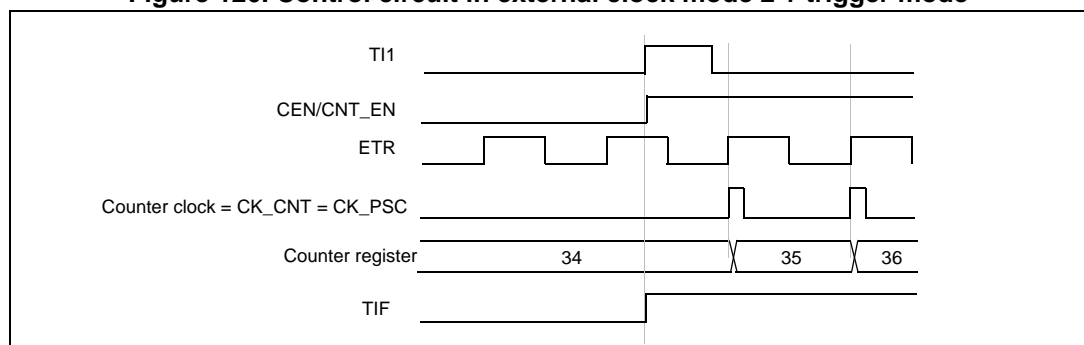
In the following example, the upcounter is incremented at each rising edge of the ETR signal as soon as a rising edge of TI1 occurs:

1. Configure the external trigger input circuit by programming the TIMx\_SMCR register as follows:
  - ETF = 0000: no filter
  - ETPS = 00: prescaler disabled
  - ETP = 0: detection of rising edges on ETR and ECE=1 to enable the external clock mode 2.
2. Configure the channel 1 as follows, to detect rising edges on TI:
  - IC1F = 0000: no filter.
  - The capture prescaler is not used for triggering and does not need to be configured.
  - CC1S = 01 in TIMx\_CCMR1 register to select only the input capture source
  - CC1P = 0 in TIMx\_CCER register to validate the polarity (and detect rising edge only).
3. Configure the timer in trigger mode by writing SMS=110 in TIMx\_SMCR register. Select TI1 as the input source by writing TS=101 in TIMx\_SMCR register.

A rising edge on TI1 enables the counter and sets the TIF flag. The counter then counts on ETR rising edges.

The delay between the rising edge of the ETR signal and the actual reset of the counter is due to the resynchronization circuit on ETRP input.

**Figure 126. Control circuit in external clock mode 2 + trigger mode**



### 13.3.15 Timer synchronization

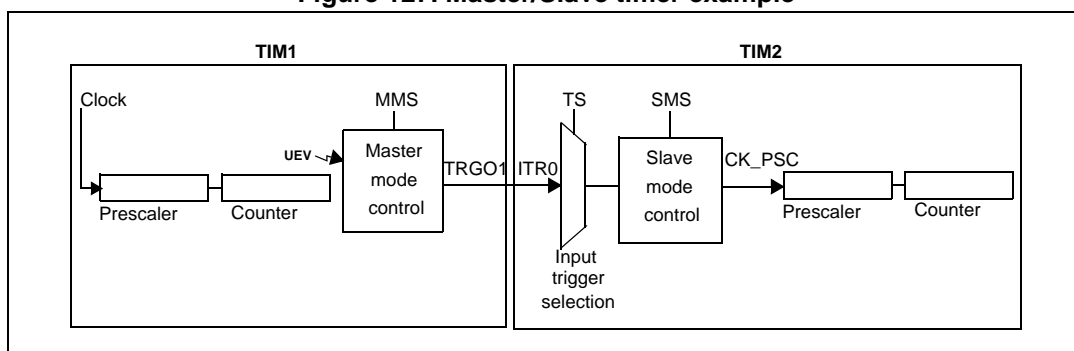
The TIMx timers are linked together internally for timer synchronization or chaining. When one Timer is configured in Master Mode, it can reset, start, stop or clock the counter of another Timer configured in Slave Mode.

*Figure 127: Master/Slave timer example* presents an overview of the trigger selection and the master mode selection blocks.

*Note:* The clock of the slave timer must be enabled prior to receiving events from the master timer, and must not be changed on-the-fly while triggers are received from the master timer.

### Using one timer as prescaler for another timer

Figure 127. Master/Slave timer example



For example, you can configure Timer 1 to act as a prescaler for Timer 2. Refer to [Figure 127](#). To do this:

- Configure Timer 1 in master mode so that it outputs a periodic trigger signal on each update event UEV. If you write MMS=010 in the TIM1\_CR2 register, a rising edge is output on TRGO1 each time an update event is generated.
- To connect the TRGO1 output of Timer 1 to Timer 2, Timer 2 must be configured in slave mode using ITR0 as internal trigger. You select this through the TS bits in the TIM2\_SMCR register (writing TS=000).
- Then you put the slave mode controller in external clock mode 1 (write SMS=111 in the TIM2\_SMCR register). This causes Timer 2 to be clocked by the rising edge of the periodic Timer 1 trigger signal (which correspond to the timer 1 counter overflow).
- Finally both timers must be enabled by setting their respective CEN bits (TIMx\_CR1 register).

*Note:* If OCx is selected on Timer 1 as trigger output (MMS=1xx), its rising edge is used to clock the counter of timer 2.

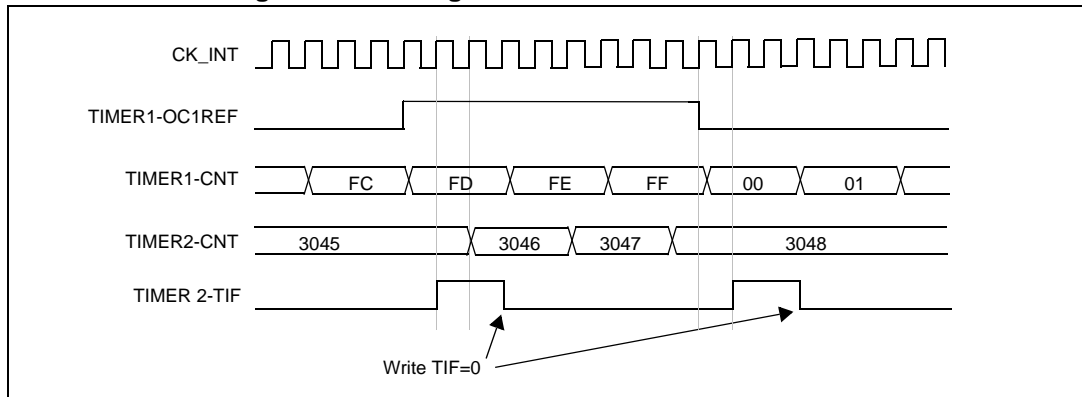
### Using one timer to enable another timer

In this example, we control the enable of Timer 2 with the output compare 1 of Timer 1. Refer to [Figure 127](#) for connections. Timer 2 counts on the divided internal clock only when OC1REF of Timer 1 is high. Both counter clock frequencies are divided by 3 by the prescaler compared to CK\_INT ( $f_{CK\_CNT} = f_{CK\_INT}/3$ ).

- Configure Timer 1 master mode to send its Output Compare 1 Reference (OC1REF) signal as trigger output (MMS=100 in the TIM1\_CR2 register).
- Configure the Timer 1 OC1REF waveform (TIM1\_CCMR1 register).
- Configure Timer 2 to get the input trigger from Timer 1 (TS=000 in the TIM2\_SMCR register).
- Configure Timer 2 in gated mode (SMS=101 in TIM2\_SMCR register).
- Enable Timer 2 by writing '1' in the CEN bit (TIM2\_CR1 register).
- Start Timer 1 by writing '1' in the CEN bit (TIM1\_CR1 register).

*Note:* The counter 2 clock is not synchronized with counter 1, this mode only affects the Timer 2 counter enable signal.

Figure 128. Gating timer 2 with OC1REF of timer 1

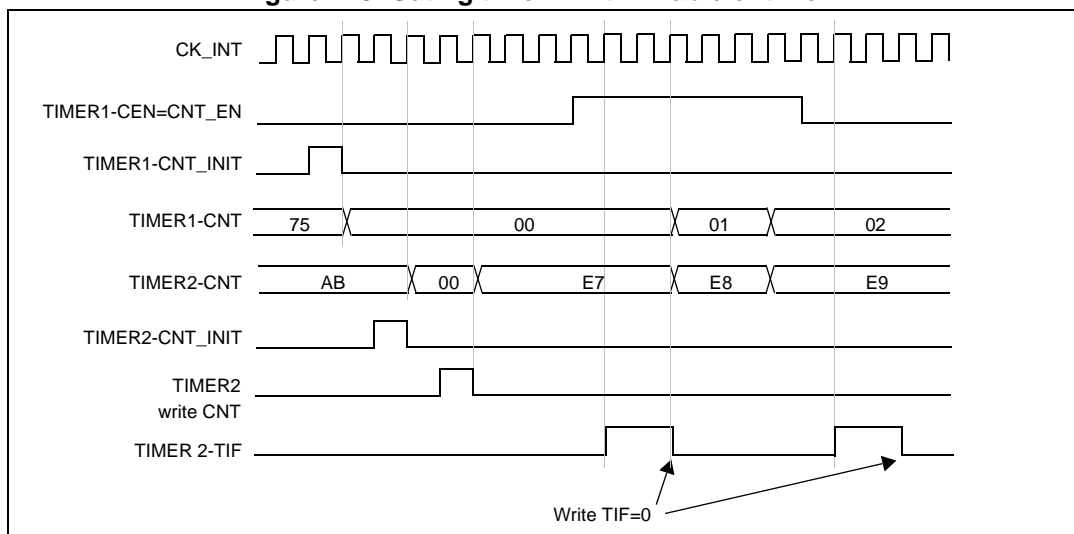


In the example in [Figure 162](#), the Timer 2 counter and prescaler are not initialized before being started. So they start counting from their current value. It is possible to start from a given value by resetting both timers before starting Timer 1. You can then write any value you want in the timer counters. The timers can easily be reset by software using the UG bit in the TIMx\_EGR registers.

In the next example, we synchronize Timer 1 and Timer 2. Timer 1 is the master and starts from 0. Timer 2 is the slave and starts from 0xE7. The prescaler ratio is the same for both timers. Timer 2 stops when Timer 1 is disabled by writing '0' to the CEN bit in the TIM1\_CR1 register:

- Configure Timer 1 master mode to send its Output Compare 1 Reference (OC1REF) signal as trigger output (MMS=100 in the TIM1\_CR2 register).
- Configure the Timer 1 OC1REF waveform (TIM1\_CCMR1 register).
- Configure Timer 2 to get the input trigger from Timer 1 (TS=000 in the TIM2\_SMCR register).
- Configure Timer 2 in gated mode (SMS=101 in TIM2\_SMCR register).
- Reset Timer 1 by writing '1' in UG bit (TIM1\_EGR register).
- Reset Timer 2 by writing '1' in UG bit (TIM2\_EGR register).
- Initialize Timer 2 to 0xE7 by writing '0xE7' in the timer 2 counter (TIM2\_CNT).
- Enable Timer 2 by writing '1' in the CEN bit (TIM2\_CR1 register).
- Start Timer 1 by writing '1' in the CEN bit (TIM1\_CR1 register).
- Stop Timer 1 by writing '0' in the CEN bit (TIM1\_CR1 register).

Figure 129. Gating timer 2 with Enable of timer 1

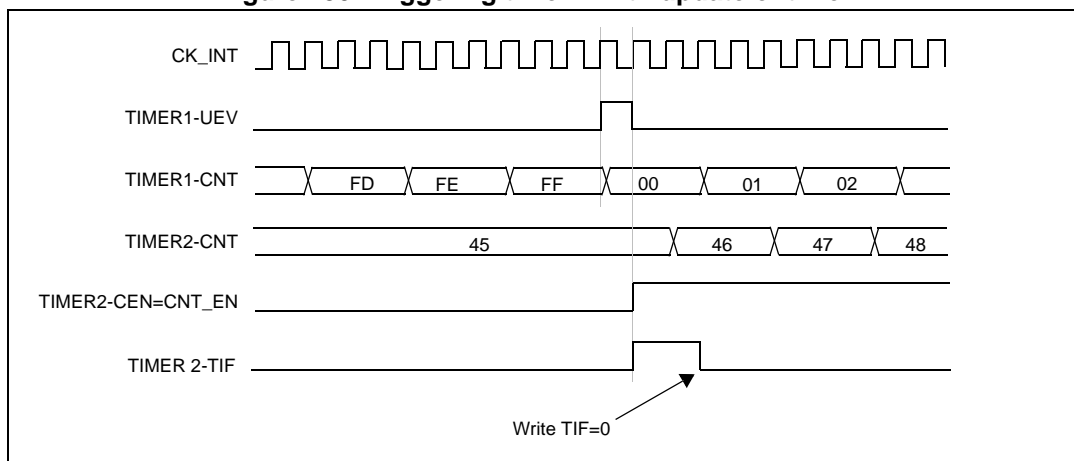


**Using one timer to start another timer**

In this example, we set the enable of Timer 2 with the update event of Timer 1. Refer to [Figure 127](#) for connections. Timer 2 starts counting from its current value (which can be nonzero) on the divided internal clock as soon as the update event is generated by Timer 1. When Timer 2 receives the trigger signal its CEN bit is automatically set and the counter counts until we write '0 to the CEN bit in the TIM2\_CR1 register. Both counter clock frequencies are divided by 3 by the prescaler compared to CK\_INT ( $f_{CK\_CNT} = f_{CK\_INT}/3$ ).

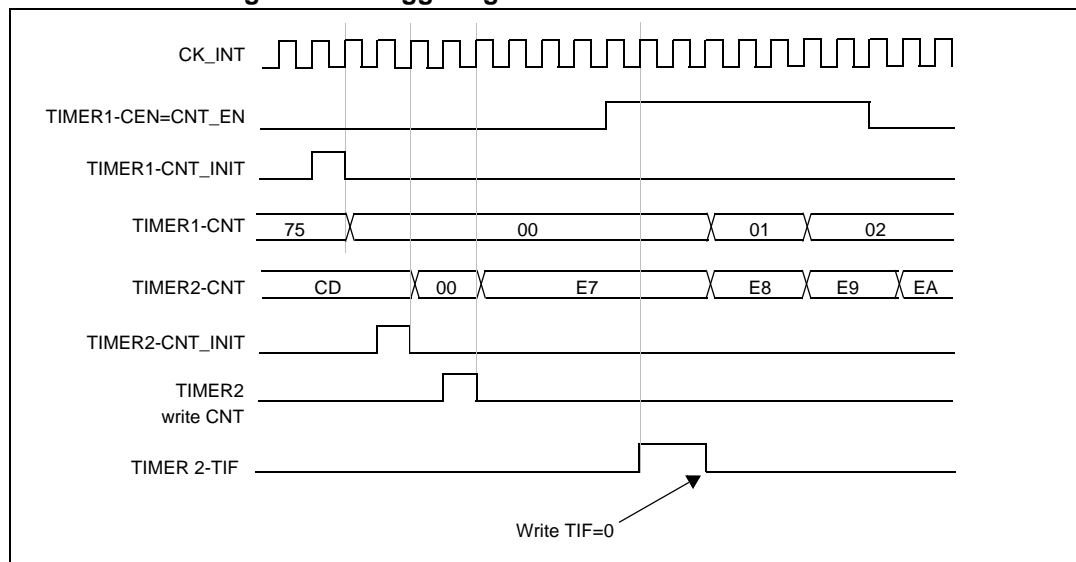
- Configure Timer 1 master mode to send its Update Event (UEV) as trigger output (MMS=010 in the TIM1\_CR2 register).
- Configure the Timer 1 period (TIM1\_ARR registers).
- Configure Timer 2 to get the input trigger from Timer 1 (TS=000 in the TIM2\_SMCR register).
- Configure Timer 2 in trigger mode (SMS=110 in TIM2\_SMCR register).
- Start Timer 1 by writing '1 in the CEN bit (TIM1\_CR1 register).

Figure 130. Triggering timer 2 with update of timer 1



As in the previous example, you can initialize both counters before starting counting. [Figure 131](#) shows the behavior with the same configuration as in [Figure 162](#) but in trigger mode instead of gated mode (SMS=110 in the TIM2\_SMCR register).

**Figure 131. Triggering timer 2 with Enable of timer 1**



**Starting 2 timers synchronously in response to an external trigger**

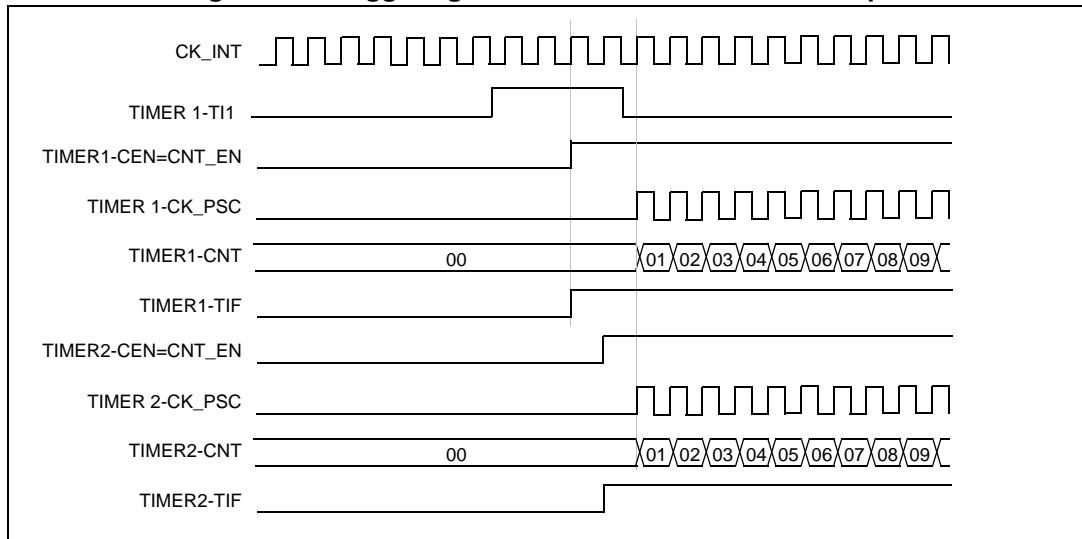
In this example, we set the enable of timer 1 when its TI1 input rises, and the enable of Timer 2 with the enable of Timer 1. Refer to [Figure 127](#) for connections. To ensure the counters are aligned, Timer 1 must be configured in Master/Slave mode (slave with respect to TI1, master with respect to Timer 2):

- Configure Timer 1 master mode to send its Enable as trigger output (MMS=001 in the TIM1\_CR2 register).
- Configure Timer 1 slave mode to get the input trigger from TI1 (TS=100 in the TIM1\_SMCR register).
- Configure Timer 1 in trigger mode (SMS=110 in the TIM1\_SMCR register).
- Configure the Timer 1 in Master/Slave mode by writing MSM=1 (TIM1\_SMCR register).
- Configure Timer 2 to get the input trigger from Timer 1 (TS=000 in the TIM2\_SMCR register).
- Configure Timer 2 in trigger mode (SMS=110 in the TIM2\_SMCR register).

When a rising edge occurs on TI1 (Timer 1), both counters starts counting synchronously on the internal clock and both TIF flags are set.

*Note:* In this example both timers are initialized before starting (by setting their respective UG bits). Both counters starts from 0, but you can easily insert an offset between them by writing any of the counter registers (TIMx\_CNT). You can see that the master/slave mode insert a delay between CNT\_EN and CK\_PSC on timer 1.

Figure 132. Triggering timer 1 and 2 with timer 1 TI1 input



### 13.3.16 Debug mode

When the microcontroller enters debug mode (Cortex<sup>®</sup>-M4 with FPU core - halted), the TIMx counter either continues to work normally or stops, depending on DBG\_TIMx\_STOP configuration bit in DBGMCU module. For more details, refer to [Section 23.16.2: Debug support for timers, watchdog and I2C](#).

## 13.4 TIM2 to TIM5 registers

Refer to [Section 1.1 on page 34](#) for a list of abbreviations used in register descriptions.

The 32-bit peripheral registers have to be written by words (32 bits). All other peripheral registers have to be written by half-words (16 bits) or words (32 bits). Read accesses can be done by bytes (8 bits), half-words (16 bits) or words (32 bits).

### 13.4.1 TIMx control register 1 (TIMx\_CR1)

Address offset: 0x00

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved						CKD[1:0]		ARPE	CMS		DIR	OPM	URS	UDIS	CEN
						rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 15:10 Reserved, must be kept at reset value.

Bits 9:8 **CKD**: Clock division

This bit-field indicates the division ratio between the timer clock (CK\_INT) frequency and sampling clock used by the digital filters (ETR, Tlx),

00:  $t_{DTS} = t_{CK\_INT}$

01:  $t_{DTS} = 2 \times t_{CK\_INT}$

10:  $t_{DTS} = 4 \times t_{CK\_INT}$

11: Reserved

Bit 7 **ARPE**: Auto-reload preload enable

0: TIMx\_ARR register is not buffered

1: TIMx\_ARR register is buffered

Bits 6:5 **CMS**: Center-aligned mode selection

00: Edge-aligned mode. The counter counts up or down depending on the direction bit (DIR).

01: Center-aligned mode 1. The counter counts up and down alternatively. Output compare interrupt flags of channels configured in output (CCxS=00 in TIMx\_CCMRx register) are set only when the counter is counting down.

10: Center-aligned mode 2. The counter counts up and down alternatively. Output compare interrupt flags of channels configured in output (CCxS=00 in TIMx\_CCMRx register) are set only when the counter is counting up.

11: Center-aligned mode 3. The counter counts up and down alternatively. Output compare interrupt flags of channels configured in output (CCxS=00 in TIMx\_CCMRx register) are set both when the counter is counting up or down.

*Note: It is not allowed to switch from edge-aligned mode to center-aligned mode as long as the counter is enabled (CEN=1)*

Bit 4 **DIR**: Direction

0: Counter used as upcounter

1: Counter used as downcounter

*Note: This bit is read only when the timer is configured in Center-aligned mode or Encoder mode.*

Bit 3 **OPM**: One-pulse mode

0: Counter is not stopped at update event

1: Counter stops counting at the next update event (clearing the bit CEN)



**Bit 2 URS:** Update request source

This bit is set and cleared by software to select the UEV event sources.

0: Any of the following events generate an update interrupt or DMA request if enabled.

These events can be:

- Counter overflow/underflow
- Setting the UG bit
- Update generation through the slave mode controller

1: Only counter overflow/underflow generates an update interrupt or DMA request if enabled.

**Bit 1 UDIS:** Update disable

This bit is set and cleared by software to enable/disable UEV event generation.

0: UEV enabled. The Update (UEV) event is generated by one of the following events:

- Counter overflow/underflow
- Setting the UG bit
- Update generation through the slave mode controller

Buffered registers are then loaded with their preload values.

1: UEV disabled. The Update event is not generated, shadow registers keep their value (ARR, PSC, CCRx). However the counter and the prescaler are reinitialized if the UG bit is set or if a hardware reset is received from the slave mode controller.

**Bit 0 CEN:** Counter enable

0: Counter disabled

1: Counter enabled

*Note: External clock, gated mode and encoder mode can work only if the CEN bit has been previously set by software. However trigger mode can set the CEN bit automatically by hardware.*

CEN is cleared automatically in one-pulse mode, when an update event occurs.

### 13.4.2 TIMx control register 2 (TIMx\_CR2)

Address offset: 0x04

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
Reserved								TI1S	MMS[2:0]			CCDS	Reserved			
								rw	rw	rw	rw	rw				

Bits 15:8 Reserved, must be kept at reset value.

Bit 7 **TI1S**: T11 selection

- 0: The TIMx\_CH1 pin is connected to T11 input
- 1: The TIMx\_CH1, CH2 and CH3 pins are connected to the T11 input (XOR combination)

Bits 6:4 **MMS[2:0]**: Master mode selection

These bits allow to select the information to be sent in master mode to slave timers for synchronization (TRGO). The combination is as follows:

000: **Reset** - the UG bit from the TIMx\_EGR register is used as trigger output (TRGO). If the reset is generated by the trigger input (slave mode controller configured in reset mode) then the signal on TRGO is delayed compared to the actual reset.

001: **Enable** - the Counter enable signal, CNT\_EN, is used as trigger output (TRGO). It is useful to start several timers at the same time or to control a window in which a slave timer is enabled. The Counter Enable signal is generated by a logic OR between CEN control bit and the trigger input when configured in gated mode.

When the Counter Enable signal is controlled by the trigger input, there is a delay on TRGO, except if the master/slave mode is selected (see the MSM bit description in TIMx\_SMCR register).

010: **Update** - The update event is selected as trigger output (TRGO). For instance a master timer can then be used as a prescaler for a slave timer.

011: **Compare Pulse** - The trigger output send a positive pulse when the CC1IF flag is to be set (even if it was already high), as soon as a capture or a compare match occurred. (TRGO)

100: **Compare** - OC1REF signal is used as trigger output (TRGO)

101: **Compare** - OC2REF signal is used as trigger output (TRGO)

110: **Compare** - OC3REF signal is used as trigger output (TRGO)

111: **Compare** - OC4REF signal is used as trigger output (TRGO)

*Note: The clock of the slave timer and ADC must be enabled prior to receiving events from the master timer, and must not be changed on-the-fly while triggers are received from the master timer.*

Bit 3 **CCDS**: Capture/compare DMA selection

- 0: CCx DMA request sent when CCx event occurs
- 1: CCx DMA requests sent when update event occurs

Bits 2:0 Reserved, must be kept at reset value.

### 13.4.3 TIMx slave mode control register (TIMx\_SMCR)

Address offset: 0x08

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
ETP	ECE	ETPS[1:0]		ETF[3:0]				MSM	TS[2:0]			Res.	SMS[2:0]		
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw		rw	rw	rw

Bit 15 **ETP**: External trigger polarity

This bit selects whether ETR or  $\overline{ETR}$  is used for trigger operations

0: ETR is noninverted, active at high level or rising edge

1: ETR is inverted, active at low level or falling edge

Bit 14 **ECE**: External clock enable

This bit enables External clock mode 2.

0: External clock mode 2 disabled

1: External clock mode 2 enabled. The counter is clocked by any active edge on the ETRF signal.

1: Setting the ECE bit has the same effect as selecting external clock mode 1 with TRGI connected to ETRF (SMS=111 and TS=111).

2: It is possible to simultaneously use external clock mode 2 with the following slave modes: reset mode, gated mode and trigger mode. Nevertheless, TRGI must not be connected to ETRF in this case (TS bits must not be 111).

3: If external clock mode 1 and external clock mode 2 are enabled at the same time, the external clock input is ETRF.

Bits 13:12 **ETPS**: External trigger prescaler

External trigger signal ETRP frequency must be at most 1/4 of CK\_INT frequency. A prescaler can be enabled to reduce ETRP frequency. It is useful when inputting fast external clocks.

00: Prescaler OFF

01: ETRP frequency divided by 2

10: ETRP frequency divided by 4

11: ETRP frequency divided by 8

Bits 11:8 **ETF[3:0]**: External trigger filter

This bit-field then defines the frequency used to sample ETRP signal and the length of the digital filter applied to ETRP. The digital filter is made of an event counter in which N events are needed to validate a transition on the output:

0000: No filter, sampling is done at  $f_{DTS}$

0001:  $f_{SAMPLING}=f_{CK\_INT}$ , N=2

0010:  $f_{SAMPLING}=f_{CK\_INT}$ , N=4

0011:  $f_{SAMPLING}=f_{CK\_INT}$ , N=8

0100:  $f_{SAMPLING}=f_{DTS}/2$ , N=6

0101:  $f_{SAMPLING}=f_{DTS}/2$ , N=8

0110:  $f_{SAMPLING}=f_{DTS}/4$ , N=6

0111:  $f_{SAMPLING}=f_{DTS}/4$ , N=8

1000:  $f_{SAMPLING}=f_{DTS}/8$ , N=6

1001:  $f_{SAMPLING}=f_{DTS}/8$ , N=8

1010:  $f_{SAMPLING}=f_{DTS}/16$ , N=5

1011:  $f_{SAMPLING}=f_{DTS}/16$ , N=6

1100:  $f_{SAMPLING}=f_{DTS}/16$ , N=8

1101:  $f_{SAMPLING}=f_{DTS}/32$ , N=5

1110:  $f_{SAMPLING}=f_{DTS}/32$ , N=6

1111:  $f_{SAMPLING}=f_{DTS}/32$ , N=8

Bit 7 **MSM**: Master/Slave mode

0: No action

1: The effect of an event on the trigger input (TRGI) is delayed to allow a perfect synchronization between the current timer and its slaves (through TRGO). It is useful if we want to synchronize several timers on a single external event.

Bits 6:4 **TS**: Trigger selection

This bit-field selects the trigger input to be used to synchronize the counter.

000: Internal Trigger 0 (ITR0).

001: Internal Trigger 1 (ITR1).

010: Internal Trigger 2 (ITR2).

011: Internal Trigger 3 (ITR3).

100: T11 Edge Detector (TI1F\_ED)

101: Filtered Timer Input 1 (TI1FP1)

110: Filtered Timer Input 2 (TI2FP2)

111: External Trigger input (ETRF)

See [Table 54: TIMx internal trigger connection on page 352](#) for more details on ITRx meaning for each Timer.*Note: These bits must be changed only when they are not used (e.g. when SMS=000) to avoid wrong edge detections at the transition.*

## Bit 3 Reserved, must be kept at reset value.

Bits 2:0 **SMS**: Slave mode selection

When external signals are selected the active edge of the trigger signal (TRGI) is linked to the polarity selected on the external input (see Input Control register and Control Register description).

000: Slave mode disabled - if CEN = '1 then the prescaler is clocked directly by the internal clock.

001: Encoder mode 1 - Counter counts up/down on TI2FP1 edge depending on TI1FP2 level.

010: Encoder mode 2 - Counter counts up/down on TI1FP2 edge depending on TI2FP1 level.

011: Encoder mode 3 - Counter counts up/down on both TI1FP1 and TI2FP2 edges depending on the level of the other input.

100: Reset Mode - Rising edge of the selected trigger input (TRGI) reinitializes the counter and generates an update of the registers.

101: Gated Mode - The counter clock is enabled when the trigger input (TRGI) is high. The counter stops (but is not reset) as soon as the trigger becomes low. Both start and stop of the counter are controlled.

110: Trigger Mode - The counter starts at a rising edge of the trigger TRGI (but it is not reset). Only the start of the counter is controlled.

111: External Clock Mode 1 - Rising edges of the selected trigger (TRGI) clock the counter.

*Note: The gated mode must not be used if TI1F\_ED is selected as the trigger input (TS=100). Indeed, TI1F\_ED outputs 1 pulse for each transition on TI1F, whereas the gated mode checks the level of the trigger signal.**The clock of the slave timer must be enabled prior to receiving events from the master timer, and must not be changed on-the-fly while triggers are received from the master timer.*

Table 54. TIMx internal trigger connection

Slave TIM	ITR0 (TS = 000)	ITR1 (TS = 001)	ITR2 (TS = 010)	ITR3 (TS = 011)
TIM2	TIM1_TRGO	Reserved	TIM3_TRGO	TIM4_TRGO
TIM3	TIM1_TRGO	TIM2_TRGO	TIM5_TRGO	TIM4_TRGO
TIM4	TIM1_TRGO	TIM2_TRGO	TIM3_TRGO	Reserved
TIM5	TIM2_TRGO	TIM3_TRGO	TIM4_TRGO	Reserved

### 13.4.4 TIMx DMA/Interrupt enable register (TIMx\_DIER)

Address offset: 0x0C

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Res.	TDE	Res	CC4DE	CC3DE	CC2DE	CC1DE	UDE	Res.	TIE	Res	CC4IE	CC3IE	CC2IE	CC1IE	UIE
	rw		rw	rw	rw	rw	rw		rw		rw	rw	rw	rw	rw

- Bit 15 Reserved, must be kept at reset value.
- Bit 14 **TDE**: Trigger DMA request enable  
 0: Trigger DMA request disabled.  
 1: Trigger DMA request enabled.
- Bit 13 Reserved, always read as 0
- Bit 12 **CC4DE**: Capture/Compare 4 DMA request enable  
 0: CC4 DMA request disabled.  
 1: CC4 DMA request enabled.
- Bit 11 **CC3DE**: Capture/Compare 3 DMA request enable  
 0: CC3 DMA request disabled.  
 1: CC3 DMA request enabled.
- Bit 10 **CC2DE**: Capture/Compare 2 DMA request enable  
 0: CC2 DMA request disabled.  
 1: CC2 DMA request enabled.
- Bit 9 **CC1DE**: Capture/Compare 1 DMA request enable  
 0: CC1 DMA request disabled.  
 1: CC1 DMA request enabled.
- Bit 8 **UDE**: Update DMA request enable  
 0: Update DMA request disabled.  
 1: Update DMA request enabled.
- Bit 7 Reserved, must be kept at reset value.
- Bit 6 **TIE**: Trigger interrupt enable  
 0: Trigger interrupt disabled.  
 1: Trigger interrupt enabled.
- Bit 5 Reserved, must be kept at reset value.
- Bit 4 **CC4IE**: Capture/Compare 4 interrupt enable  
 0: CC4 interrupt disabled.  
 1: CC4 interrupt enabled.

- Bit 2 **CC2IE**: Capture/Compare 2 interrupt enable  
 0: CC2 interrupt disabled  
 1: CC2 interrupt enabled
- Bit 1 **CC1IE**: Capture/Compare 1 interrupt enable  
 0: CC1 interrupt disabled  
 1: CC1 interrupt enabled
- Bit 0 **UIE**: Update interrupt enable  
 0: Update interrupt disabled  
 1: Update interrupt enabled

### 13.4.5 TIMx status register (TIMx\_SR)

Address offset: 0x10

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0		
Reserved				CC4OF	CC3OF	CC2OF	CC1OF	Reserved			TIF	Res	CC4IF	CC3IF	CC2IF	CC1IF	UIF
				rc_w0	rc_w0	rc_w0	rc_w0				rc_w0		rc_w0	rc_w0	rc_w0	rc_w0	rc_w0

- Bits 15:13 Reserved, must be kept at reset value.
- Bit 12 **CC4OF**: Capture/Compare 4 overcapture flag  
refer to CC1OF description
- Bit 11 **CC3OF**: Capture/Compare 3 overcapture flag  
refer to CC1OF description
- Bit 10 **CC2OF**: Capture/compare 2 overcapture flag  
refer to CC1OF description
- Bit 9 **CC1OF**: Capture/Compare 1 overcapture flag  
 This flag is set by hardware only when the corresponding channel is configured in input capture mode. It is cleared by software by writing it to '0'.  
 0: No overcapture has been detected  
 1: The counter value has been captured in TIMx\_CCR1 register while CC1IF flag was already set
- Bits 8:7 Reserved, must be kept at reset value.
- Bit 6 **TIF**: Trigger interrupt flag  
 This flag is set by hardware on trigger event (active edge detected on TRGI input when the slave mode controller is enabled in all modes but gated mode. It is set when the counter starts or stops when gated mode is selected. It is cleared by software.  
 0: No trigger event occurred  
 1: Trigger interrupt pending
- Bit 5 Reserved, must be kept at reset value.
- Bit 4 **CC4IF**: Capture/Compare 4 interrupt flag  
refer to CC1IF description
- Bit 3 **CC3IF**: Capture/Compare 3 interrupt flag  
refer to CC1IF description

- Bit 2 **CC2IF**: Capture/Compare 2 interrupt flag  
refer to CC1IF description
- Bit 1 **CC1IF**: Capture/compare 1 interrupt flag  
**If channel CC1 is configured as output:**  
This flag is set by hardware when the counter matches the compare value, with some exception in center-aligned mode (refer to the CMS bits in the TIMx\_CR1 register description). It is cleared by software.  
0: No match  
1: The content of the counter TIMx\_CNT matches the content of the TIMx\_CCR1 register. When the contents of TIMx\_CCR1 are greater than the contents of TIMx\_ARR, the CC1IF bit goes high on the counter overflow (in upcounting and up/down-counting modes) or underflow (in downcounting mode)  
**If channel CC1 is configured as input:**  
This bit is set by hardware on a capture. It is cleared by software or by reading the TIMx\_CCR1 register.  
0: No input capture occurred  
1: The counter value has been captured in TIMx\_CCR1 register (An edge has been detected on IC1 which matches the selected polarity)
- Bit 0 **UIF**: Update interrupt flag
- " This bit is set by hardware on an update event. It is cleared by software.  
0: No update occurred.  
1: Update interrupt pending. This bit is set by hardware when the registers are updated:
  - " At overflow or underflow (for TIM2 to TIM5) and if UDIS=0 in the TIMx\_CR1 register.
  - " When CNT is reinitialized by software using the UG bit in TIMx\_EGR register, if URS=0 and UDIS=0 in the TIMx\_CR1 register.  
When CNT is reinitialized by a trigger event (refer to the synchro control register description), if URS=0 and UDIS=0 in the TIMx\_CR1 register.

### 13.4.6 TIMx event generation register (TIMx\_EGR)

Address offset: 0x14

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved									TG	Res.	CC4G	CC3G	CC2G	CC1G	UG
									W		W	W	W	W	

Bits 15:7 Reserved, must be kept at reset value.

Bit 6 **TG**: Trigger generation

This bit is set by software in order to generate an event, it is automatically cleared by hardware.

0: No action

1: The TIF flag is set in TIMx\_SR register. Related interrupt or DMA transfer can occur if enabled.

Bit 5 Reserved, must be kept at reset value.

Bit 4 **CC4G**: Capture/compare 4 generation  
refer to CC1G description

Bit 3 **CC3G**: Capture/compare 3 generation  
refer to CC1G description

Bit 2 **CC2G**: Capture/compare 2 generation  
refer to CC1G description

Bit 1 **CC1G**: Capture/compare 1 generation

This bit is set by software in order to generate an event, it is automatically cleared by hardware.

0: No action

1: A capture/compare event is generated on channel 1:

**If channel CC1 is configured as output:**

CC1IF flag is set, Corresponding interrupt or DMA request is sent if enabled.

**If channel CC1 is configured as input:**

The current value of the counter is captured in TIMx\_CCR1 register. The CC1IF flag is set, the corresponding interrupt or DMA request is sent if enabled. The CC1OF flag is set if the CC1IF flag was already high.

Bit 0 **UG**: Update generation

This bit can be set by software, it is automatically cleared by hardware.

0: No action

1: Re-initialize the counter and generates an update of the registers. Note that the prescaler counter is cleared too (anyway the prescaler ratio is not affected). The counter is cleared if the center-aligned mode is selected or if DIR=0 (upcounting), else it takes the auto-reload value (TIMx\_ARR) if DIR=1 (downcounting).



### 13.4.7 TIMx capture/compare mode register 1 (TIMx\_CCMR1)

Address offset: 0x18

Reset value: 0x0000

The channels can be used in input (capture mode) or in output (compare mode). The direction of a channel is defined by configuring the corresponding CCxS bits. All the other bits of this register have a different function in input and in output mode. For a given bit, OCxx describes its function when the channel is configured in output, ICxx describes its function when the channel is configured in input. So you must take care that the same bit can have a different meaning for the input stage and for the output stage.

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
OC2CE	OC2M[2:0]			OC2PE	OC2FE	CC2S[1:0]		OC1CE	OC1M[2:0]			OC1PE	OC1FE	CC1S[1:0]	
IC2F[3:0]				IC2PSC[1:0]				IC1F[3:0]				IC1PSC[1:0]			
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

#### Output compare mode

Bit 15 **OC2CE**: Output compare 2 clear enable

Bits 14:12 **OC2M[2:0]**: Output compare 2 mode

Bit 11 **OC2PE**: Output compare 2 preload enable

Bit 10 **OC2FE**: Output compare 2 fast enable

Bits 9:8 **CC2S[1:0]**: Capture/Compare 2 selection

This bit-field defines the direction of the channel (input/output) as well as the used input.

00: CC2 channel is configured as output

01: CC2 channel is configured as input, IC2 is mapped on TI2

10: CC2 channel is configured as input, IC2 is mapped on TI1

11: CC2 channel is configured as input, IC2 is mapped on TRC. This mode is working only if an internal trigger input is selected through the TS bit (TIMx\_SMCR register)

*Note: CC2S bits are writable only when the channel is OFF (CC2E = 0 in TIMx\_CCER).*

Bit 7 **OC1CE**: Output compare 1 clear enable

OC1CE: Output Compare 1 Clear Enable

0: OC1Ref is not affected by the ETRF input

1: OC1Ref is cleared as soon as a High level is detected on ETRF input

Bits 6:4 **OC1M**: Output compare 1 mode

These bits define the behavior of the output reference signal OC1REF from which OC1 and OC1N are derived. OC1REF is active high whereas OC1 and OC1N active level depends on CC1P and CC1NP bits.

000: Frozen - The comparison between the output compare register TIMx\_CCR1 and the counter TIMx\_CNT has no effect on the outputs.(this mode is used to generate a timing base).

001: Set channel 1 to active level on match. OC1REF signal is forced high when the counter TIMx\_CNT matches the capture/compare register 1 (TIMx\_CCR1).

010: Set channel 1 to inactive level on match. OC1REF signal is forced low when the counter TIMx\_CNT matches the capture/compare register 1 (TIMx\_CCR1).

011: Toggle - OC1REF toggles when TIMx\_CNT=TIMx\_CCR1.

100: Force inactive level - OC1REF is forced low.

101: Force active level - OC1REF is forced high.

110: PWM mode 1 - In upcounting, channel 1 is active as long as TIMx\_CNT<TIMx\_CCR1 else inactive. In downcounting, channel 1 is inactive (OC1REF=0) as long as TIMx\_CNT>TIMx\_CCR1 else active (OC1REF=1).

111: PWM mode 2 - In upcounting, channel 1 is inactive as long as TIMx\_CNT<TIMx\_CCR1 else active. In downcounting, channel 1 is active as long as TIMx\_CNT>TIMx\_CCR1 else inactive.

*Note: In PWM mode 1 or 2, the OCREF level changes only when the result of the comparison changes or when the output compare mode switches from "frozen" mode to "PWM" mode.*

Bit 3 **OC1PE**: Output compare 1 preload enable

0: Preload register on TIMx\_CCR1 disabled. TIMx\_CCR1 can be written at anytime, the new value is taken in account immediately.

1: Preload register on TIMx\_CCR1 enabled. Read/Write operations access the preload register. TIMx\_CCR1 preload value is loaded in the active register at each update event.

*Note: 1: These bits can not be modified as long as LOCK level 3 has been programmed (LOCK bits in TIMx\_BDTR register) and CC1S=00 (the channel is configured in output).*

*2: The PWM mode can be used without validating the preload register only in one-pulse mode (OPM bit set in TIMx\_CR1 register). Else the behavior is not guaranteed.*

Bit 2 **OC1FE**: Output compare 1 fast enable

This bit is used to accelerate the effect of an event on the trigger in input on the CC output.  
0: CC1 behaves normally depending on counter and CCR1 values even when the trigger is ON. The minimum delay to activate CC1 output when an edge occurs on the trigger input is 5 clock cycles.

1: An active edge on the trigger input acts like a compare match on CC1 output. Then, OC is set to the compare level independently from the result of the comparison. Delay to sample the trigger input and to activate CC1 output is reduced to 3 clock cycles. OC1FE acts only if the channel is configured in PWM1 or PWM2 mode.

Bits 1:0 **CC1S**: Capture/Compare 1 selection

This bit-field defines the direction of the channel (input/output) as well as the used input.

00: CC1 channel is configured as output.

01: CC1 channel is configured as input, IC1 is mapped on TI1.

10: CC1 channel is configured as input, IC1 is mapped on TI2.

11: CC1 channel is configured as input, IC1 is mapped on TRC. This mode is working only if an internal trigger input is selected through TS bit (TIMx\_SMCR register)

*Note: CC1S bits are writable only when the channel is OFF (CC1E = 0 in TIMx\_CCER).*

## Input capture mode

Bits 15:12 **IC2F**: Input capture 2 filter

Bits 11:10 **IC2PSC[1:0]**: Input capture 2 prescaler

Bits 9:8 **CC2S**: Capture/compare 2 selection

This bit-field defines the direction of the channel (input/output) as well as the used input.  
00: CC2 channel is configured as output.

01: CC2 channel is configured as input, IC2 is mapped on TI2.

10: CC2 channel is configured as input, IC2 is mapped on TI1.

11: CC2 channel is configured as input, IC2 is mapped on TRC. This mode is working only if an internal trigger input is selected through TS bit (TIMx\_SMCR register)

*Note: CC2S bits are writable only when the channel is OFF (CC2E = 0 in TIMx\_CCER).*

Bits 7:4 **IC1F**: Input capture 1 filter

This bit-field defines the frequency used to sample TI1 input and the length of the digital filter applied to TI1. The digital filter is made of an event counter in which N events are needed to validate a transition on the output:

0000: No filter, sampling is done at  $f_{DTS}$

0001:  $f_{SAMPLING}=f_{CK\_INT}$ , N=2

0010:  $f_{SAMPLING}=f_{CK\_INT}$ , N=4

0011:  $f_{SAMPLING}=f_{CK\_INT}$ , N=8

0100:  $f_{SAMPLING}=f_{DTS}/2$ , N=6

0101:  $f_{SAMPLING}=f_{DTS}/2$ , N=8

0110:  $f_{SAMPLING}=f_{DTS}/4$ , N=6

0111:  $f_{SAMPLING}=f_{DTS}/4$ , N=8

1000:  $f_{SAMPLING}=f_{DTS}/8$ , N=6

1001:  $f_{SAMPLING}=f_{DTS}/8$ , N=8

1010:  $f_{SAMPLING}=f_{DTS}/16$ , N=5

1011:  $f_{SAMPLING}=f_{DTS}/16$ , N=6

1100:  $f_{SAMPLING}=f_{DTS}/16$ , N=8

1101:  $f_{SAMPLING}=f_{DTS}/32$ , N=5

1110:  $f_{SAMPLING}=f_{DTS}/32$ , N=6

1111:  $f_{SAMPLING}=f_{DTS}/32$ , N=8

Bits 3:2 **IC1PSC**: Input capture 1 prescaler

This bit-field defines the ratio of the prescaler acting on CC1 input (IC1).

The prescaler is reset as soon as CC1E=0 (TIMx\_CCER register).

00: no prescaler, capture is done each time an edge is detected on the capture input

01: capture is done once every 2 events

10: capture is done once every 4 events

11: capture is done once every 8 events

Bits 1:0 **CC1S**: Capture/Compare 1 selection

This bit-field defines the direction of the channel (input/output) as well as the used input.

00: CC1 channel is configured as output

01: CC1 channel is configured as input, IC1 is mapped on TI1

10: CC1 channel is configured as input, IC1 is mapped on TI2

11: CC1 channel is configured as input, IC1 is mapped on TRC. This mode is working only if an internal trigger input is selected through TS bit (TIMx\_SMCR register)

*Note: CC1S bits are writable only when the channel is OFF (CC1E = 0 in TIMx\_CCER).*

### 13.4.8 TIMx capture/compare mode register 2 (TIMx\_CCMR2)

Address offset: 0x1C

Reset value: 0x0000

Refer to the above CCMR1 register description.

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
OC4CE	OC4M[2:0]			OC4PE	OC4FE	CC4S[1:0]		OC3CE	OC3M[2:0]			OC3PE	OC3FE	CC3S[1:0]	
IC4F[3:0]				IC4PSC[1:0]				IC3F[3:0]				IC3PSC[1:0]			
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

#### Output compare mode

Bit 15 **OC4CE**: Output compare 4 clear enable

Bits 14:12 **OC4M**: Output compare 4 mode

Bit 11 **OC4PE**: Output compare 4 preload enable

Bit 10 **OC4FE**: Output compare 4 fast enable

Bits 9:8 **CC4S**: Capture/Compare 4 selection

This bit-field defines the direction of the channel (input/output) as well as the used input.

00: CC4 channel is configured as output

01: CC4 channel is configured as input, IC4 is mapped on TI4

10: CC4 channel is configured as input, IC4 is mapped on TI3

11: CC4 channel is configured as input, IC4 is mapped on TRC. This mode is working only if an internal trigger input is selected through TS bit (TIMx\_SMCR register)

*Note: CC4S bits are writable only when the channel is OFF (CC4E = 0 in TIMx\_CCER).*

Bit 7 **OC3CE**: Output compare 3 clear enable

Bits 6:4 **OC3M**: Output compare 3 mode

Bit 3 **OC3PE**: Output compare 3 preload enable

Bit 2 **OC3FE**: Output compare 3 fast enable

Bits 1:0 **CC3S**: Capture/Compare 3 selection

This bit-field defines the direction of the channel (input/output) as well as the used input.

00: CC3 channel is configured as output

01: CC3 channel is configured as input, IC3 is mapped on TI3

10: CC3 channel is configured as input, IC3 is mapped on TI4

11: CC3 channel is configured as input, IC3 is mapped on TRC. This mode is working only if an internal trigger input is selected through TS bit (TIMx\_SMCR register)

*Note: CC3S bits are writable only when the channel is OFF (CC3E = 0 in TIMx\_CCER).*

**Input capture mode**

Bits 15:12 **IC4F**: Input capture 4 filter

Bits 11:10 **IC4PSC**: Input capture 4 prescaler

Bits 9:8 **CC4S**: Capture/Compare 4 selection

This bit-field defines the direction of the channel (input/output) as well as the used input.

00: CC4 channel is configured as output

01: CC4 channel is configured as input, IC4 is mapped on TI4

10: CC4 channel is configured as input, IC4 is mapped on TI3

11: CC4 channel is configured as input, IC4 is mapped on TRC. This mode is working only if an internal trigger input is selected through TS bit (TIMx\_SMCR register)

*Note: CC4S bits are writable only when the channel is OFF (CC4E = 0 in TIMx\_CCER).*

Bits 7:4 **IC3F**: Input capture 3 filter

Bits 3:2 **IC3PSC**: Input capture 3 prescaler

Bits 1:0 **CC3S**: Capture/Compare 3 selection

This bit-field defines the direction of the channel (input/output) as well as the used input.

00: CC3 channel is configured as output

01: CC3 channel is configured as input, IC3 is mapped on TI3

10: CC3 channel is configured as input, IC3 is mapped on TI4

11: CC3 channel is configured as input, IC3 is mapped on TRC. This mode is working only if an internal trigger input is selected through TS bit (TIMx\_SMCR register)

*Note: CC3S bits are writable only when the channel is OFF (CC3E = 0 in TIMx\_CCER).*

**13.4.9 TIMx capture/compare enable register (TIMx\_CCER)**

Address offset: 0x20

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
CC4NP	Res.	CC4P	CC4E	CC3NP	Res.	CC3P	CC3E	CC2NP	Res.	CC2P	CC2E	CC1NP	Res.	CC1P	CC1E
rw		rw	rw	rw		rw	rw	rw		rw	rw	rw		rw	rw

Bit 15 **CC4NP**: Capture/Compare 4 output Polarity.  
Refer to CC1NP description

Bit 14 Reserved, must be kept at reset value.

Bit 13 **CC4P**: Capture/Compare 4 output Polarity.  
refer to CC1P description

Bit 12 **CC4E**: Capture/Compare 4 output enable.  
refer to CC1E description

Bit 11 **CC3NP**: Capture/Compare 3 output Polarity.  
refer to CC1NP description

Bit 10 Reserved, must be kept at reset value.

Bit 9 **CC3P**: Capture/Compare 3 output Polarity.  
refer to CC1P description



- Bit 8 **CC3E**: *Capture/Compare 3 output enable.*  
refer to CC1E description
- Bit 7 **CC2NP**: *Capture/Compare 2 output Polarity.*  
refer to CC1NP description
- Bit 6 Reserved, must be kept at reset value.
- Bit 5 **CC2P**: *Capture/Compare 2 output Polarity.*  
refer to CC1P description
- Bit 4 **CC2E**: *Capture/Compare 2 output enable.*  
refer to CC1E description
- Bit 3 **CC1NP**: *Capture/Compare 1 output Polarity.*  
CC1 channel configured as output:  
CC1NP must be kept cleared in this case.  
CC1 channel configured as input:  
This bit is used in conjunction with CC1P to define TI1FP1/TI2FP1 polarity. refer to CC1P description.
- Bit 2 Reserved, must be kept at reset value.
- Bit 1 **CC1P**: *Capture/Compare 1 output Polarity.*  
**CC1 channel configured as output:**  
0: OC1 active high  
1: OC1 active low  
**CC1 channel configured as input:**  
CC1NP/CC1P bits select TI1FP1 and TI2FP1 polarity for trigger or capture operations.  
00: noninverted/rising edge  
Circuit is sensitive to TIxFP1 rising edge (capture, trigger in reset, external clock or trigger mode), TIxFP1 is not inverted (trigger in gated mode, encoder mode).  
01: inverted/falling edge  
Circuit is sensitive to TIxFP1 falling edge (capture, trigger in reset, external clock or trigger mode), TIxFP1 is inverted (trigger in gated mode, encoder mode).  
10: reserved, do not use this configuration.  
11: noninverted/both edges  
Circuit is sensitive to both TIxFP1 rising and falling edges (capture, trigger in reset, external clock or trigger mode), TIxFP1 is not inverted (trigger in gated mode). This configuration must not be used for encoder mode.
- Bit 0 **CC1E**: *Capture/Compare 1 output enable.*  
**CC1 channel configured as output:**  
0: Off - OC1 is not active  
1: On - OC1 signal is output on the corresponding output pin  
**CC1 channel configured as input:**  
This bit determines if a capture of the counter value can actually be done into the input capture/compare register 1 (TIMx\_CCR1) or not.  
0: Capture disabled  
1: Capture enabled

**Table 55. Output control bit for standard OCx channels**

CCxE bit	OCx output state
0	Output Disabled (OCx=0, OCx_EN=0)
1	OCx=OCxREF + Polarity, OCx_EN=1

Note: The state of the external IO pins connected to the standard OCx channels depends on the OCx channel state and the GPIO registers.

### 13.4.10 TIMx counter (TIMx\_CNT)

Address offset: 0x24

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
CNT[31:16] (depending on timers)															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
CNT[15:0]															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 15:0 **CNT[15:0]**: Counter value

### 13.4.11 TIMx prescaler (TIMx\_PSC)

Address offset: 0x28

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
PSC[15:0]															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 15:0 **PSC[15:0]**: Prescaler value

The counter clock frequency CK\_CNT is equal to  $f_{CK\_PSC} / (PSC[15:0] + 1)$ .

PSC contains the value to be loaded in the active prescaler register at each update event.

### 13.4.12 TIMx auto-reload register (TIMx\_ARR)

Address offset: 0x2C

Reset value: 0x 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
ARR[31:16] (depending on timers)															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
ARR[15:0]															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 15:0 **ARR[15:0]**: Auto-reload value

ARR is the value to be loaded in the actual auto-reload register.

Refer to the [Section 13.3.1: Time-base unit on page 312](#) for more details about ARR update and behavior.

The counter is blocked while the auto-reload value is null.

### 13.4.13 TIMx capture/compare register 1 (TIMx\_CCR1)

Address offset: 0x34

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
CCR1[31:16] (depending on timers)															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
CCR1[15:0]															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 31:16 **CCR1[31:16]**: High Capture/Compare 1 value (on TIM2 and TIM5).

Bits 15:0 **CCR1[15:0]**: Low Capture/Compare 1 value

**If channel CC1 is configured as output:**

CCR1 is the value to be loaded in the actual capture/compare 1 register (preload value). It is loaded permanently if the preload feature is not selected in the TIMx\_CCMR1 register (bit OC1PE). Else the preload value is copied in the active capture/compare 1 register when an update event occurs.

The active capture/compare register contains the value to be compared to the counter TIMx\_CNT and signaled on OC1 output.

**If channel CC1 is configured as input:**

CCR1 is the counter value transferred by the last input capture 1 event (IC1).

### 13.4.14 TIMx capture/compare register 2 (TIMx\_CCR2)

Address offset: 0x38

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
CCR2[31:16] (depending on timers)															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
CCR2[15:0]															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 31:16 **CCR2[31:16]**: High Capture/Compare 2 value (on TIM2 and TIM5).

Bits 15:0 **CCR2[15:0]**: Low Capture/Compare 2 value

**If channel CC2 is configured as output:**

CCR2 is the value to be loaded in the actual capture/compare 2 register (preload value). It is loaded permanently if the preload feature is not selected in the TIMx\_CCMR register (bit OC2PE). Else the preload value is copied in the active capture/compare 2 register when an update event occurs.

The active capture/compare register contains the value to be compared to the counter TIMx\_CNT and signaled on OC2 output.

**If channel CC2 is configured as input:**

CCR2 is the counter value transferred by the last input capture 2 event (IC2).



### 13.4.15 TIMx capture/compare register 3 (TIMx\_CCR3)

Address offset: 0x3C

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
CCR3[31:16] (depending on timers)															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
CCR3[15:0]															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 31:16 **CCR3[31:16]**: High Capture/Compare 3 value (on TIM2 and TIM5).

Bits 15:0 **CCR3[15:0]**: Low Capture/Compare value

**If channel CC3 is configured as output:**

CCR3 is the value to be loaded in the actual capture/compare 3 register (preload value). It is loaded permanently if the preload feature is not selected in the TIMx\_CCMR register (bit OC3PE). Else the preload value is copied in the active capture/compare 3 register when an update event occurs.

The active capture/compare register contains the value to be compared to the counter TIMx\_CNT and signaled on OC3 output.

**If channel CC3 is configured as input:**

CCR3 is the counter value transferred by the last input capture 3 event (IC3).

### 13.4.16 TIMx capture/compare register 4 (TIMx\_CCR4)

Address offset: 0x40

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
CCR4[31:16] (depending on timers)															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
CCR4[15:0]															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 31:16 **CCR4[31:16]**: High Capture/Compare 4 value (on TIM2 and TIM5).

Bits 15:0 **CCR4[15:0]**: Low Capture/Compare value

1. if CC4 channel is configured as output (CC4S bits):

CCR4 is the value to be loaded in the actual capture/compare 4 register (preload value). It is loaded permanently if the preload feature is not selected in the TIMx\_CCMR register (bit OC4PE). Else the preload value is copied in the active capture/compare 4 register when an update event occurs.

The active capture/compare register contains the value to be compared to the counter TIMx\_CNT and signalled on OC4 output.

2. if CC4 channel is configured as input (CC4S bits in TIMx\_CCMR4 register):  
CCR4 is the counter value transferred by the last input capture 4 event (IC4).

### 13.4.17 TIMx DMA control register (TIMx\_DCR)

Address offset: 0x48

Reset value: 0x0000

	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0				
	Reserved					DBL[4:0]					Reserved					DBA[4:0]				
						rw										rw				

Bits 15:13 Reserved, must be kept at reset value.

Bits 12:8 **DBL[4:0]**: DMA burst length

This 5-bit vector defines the number of DMA transfers (the timer recognizes a burst transfer when a read or a write access is done to the TIMx\_DMAR address).

- 00000: 1 transfer,
- 00001: 2 transfers,
- 00010: 3 transfers,
- ...
- 10001: 18 transfers.

Bits 7:5 Reserved, must be kept at reset value.

Bits 4:0 **DBA[4:0]**: DMA base address

This 5-bit vector defines the base-address for DMA transfers (when read/write access are done through the TIMx\_DMAR address). DBA is defined as an offset starting from the address of the TIMx\_CR1 register.

Example:

- 00000: TIMx\_CR1,
- 00001: TIMx\_CR2,
- 00010: TIMx\_SMCR,
- ...

**Example:** Let us consider the following transfer: DBL = 7 transfers & DBA = TIMx\_CR1. In this case the transfer is done to/from 7 registers starting from the TIMx\_CR1 address.

### 13.4.18 TIMx DMA address for full transfer (TIMx\_DMAR)

Address offset: 0x4C

Reset value: 0x0000

	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	DMAB[15:0]															
	rw		rw		rw		rw		rw		rw		rw		rw	

Bits 15:0 **DMAB[15:0]**: DMA register for burst accesses

A read or write operation to the DMAR register accesses the register located at the address  $(TIMx\_CR1\ address) + (DBA + DMA\ index) \times 4$

where TIMx\_CR1 address is the address of the control register 1, DBA is the DMA base address configured in TIMx\_DCR register, DMA index is automatically controlled by the DMA transfer, and ranges from 0 to DBL (DBL configured in TIMx\_DCR).

#### Example of how to use the DMA burst feature

In this example the timer DMA burst feature is used to update the contents of the CCRx registers (x = 2, 3, 4) with the DMA transferring half words into the CCRx registers.

This is done in the following steps:

1. Configure the corresponding DMA channel as follows:
  - DMA channel peripheral address is the DMAR register address
  - DMA channel memory address is the address of the buffer in the RAM containing the data to be transferred by DMA into CCRx registers.
  - Number of data to transfer = 3 (See note below).
  - Circular mode disabled.
2. Configure the DCR register by configuring the DBA and DBL bit fields as follows:  
DBL = 3 transfers, DBA = 0xE.
3. Enable the TIMx update DMA request (set the UDE bit in the DIER register).
4. Enable TIMx
5. Enable the DMA channel

*Note:* This example is for the case where every CCRx register to be updated once. If every CCRx register is to be updated twice for example, the number of data to transfer should be 6. Let's take the example of a buffer in the RAM containing data1, data2, data3, data4, data5 and data6. The data is transferred to the CCRx registers as follows: on the first update DMA request, data1 is transferred to CCR2, data2 is transferred to CCR3, data3 is transferred to CCR4 and on the second update DMA request, data4 is transferred to CCR2, data5 is transferred to CCR3 and data6 is transferred to CCR4.

### 13.4.19 TIM2 option register (TIM2\_OR)

Address offset: 0x50

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved				ITR1_RMP		Reserved									
				rw	rw										

Bits 15:12 Reserved, must be kept at reset value.

Bits 11:10 **ITR1\_RMP**: Internal trigger 1 remap

Set and cleared by software.

00: Reserved

01: PTP trigger output is connected to TIM2\_ITR1

10: OTG FS SOF is connected to the TIM2\_ITR1 input

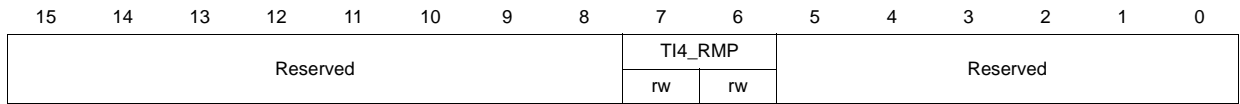
11: OTG HS SOF is connected to the TIM2\_ITR1 input

Bits 9:0 Reserved, must be kept at reset value.

**13.4.20 TIM5 option register (TIM5\_OR)**

Address offset: 0x50

Reset value: 0x0000



Bits 15:8 Reserved, must be kept at reset value.

Bits 7:6 **TI4\_RMP**: Timer Input 4 remap

Set and cleared by software.

00: TIM5 Channel4 is connected to the GPIO: Refer to the Alternate function mapping table in the datasheets.

01: the LSI internal clock is connected to the TIM5\_CH4 input for calibration purposes

10: the LSE internal clock is connected to the TIM5\_CH4 input for calibration purposes

11: the RTC wakeup interrupt is connected to TIM5\_CH4 input for calibration purposes.

Wakeup interrupt should be enabled.

Bits 5:0 Reserved, must be kept at reset value.

### 13.4.21 TIMx register map

TIMx registers are mapped as described in the table below:

**Table 56. TIM2 to TIM5 register map and reset values**

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0																			
0x00	<b>TIMx_CR1</b>	Reserved																						CKD [1:0]	ARPE	CMS [1:0]	DIR	OPM	URS	UDIS	CEN																					
	Reset value																							0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x04	<b>TIMx_CR2</b>	Reserved																						TIS	MMS[2:0]	CCDS	Reserved																									
	Reset value																							0	0	0	0	0																								
0x08	<b>TIMx_SMCR</b>	Reserved																	ETP	ECE	ETPS [1:0]	ETF[3:0]	MSM	TS[2:0]	Reserved	SMS[2:0]																										
	Reset value																		0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0																	
0x0C	<b>TIMx_DIER</b>	Reserved																	TDE	COMDE	CC4DE	CC3DE	CC2DE	CC1DE	UDE	Reserved	TIE	Reserved	CC4IE	CC3IE	CC2IE	CC1IE	UIE																			
	Reset value																		0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0				
0x10	<b>TIMx_SR</b>	Reserved																						CC4OF	CC3OF	CC2OF	CC1OF	Reserved	TIF	Reserved	CC4IF	CC3IF	CC2IF	CC1IF	UIF																	
	Reset value																							0	0	0	0	0	0	0	0	0	0	0	0	0																
0x14	<b>TIMx_EGR</b>	Reserved																						TG	Reserved	CC4G	CC3G	CC2G	CC1G	UG																						
	Reset value																							0	0	0	0	0	0	0	0																					
0x18	<b>TIMx_CCMR1</b> Output Compare mode	Reserved																	OC2CE	OC2M [2:0]	OC2PE	OC2FE	CC2S [1:0]	OC1CE	OC1M [2:0]	OC1PE	OC1FE	CC1S [1:0]																								
	Reset value																		0	0	0	0	0	0	0	0	0	0	0	0																						
	<b>TIMx_CCMR1</b> Input Capture mode	Reserved																	IC2F[3:0]	IC2PSC [1:0]	CC2S [1:0]	IC1F[3:0]	IC1PSC [1:0]	CC1S [1:0]																												
	Reset value																		0	0	0	0	0	0	0	0	0	0	0	0																						
0x1C	<b>TIMx_CCMR2</b> Output Compare mode	Reserved																	O24CE	OC4M [2:0]	OC4PE	OC4FE	CC4S [1:0]	OC3CE	OC3M [2:0]	OC3PE	OC3FE	CC3S [1:0]																								
	Reset value																		0	0	0	0	0	0	0	0	0	0	0	0																						
	<b>TIMx_CCMR2</b> Input Capture mode	Reserved																	IC4F[3:0]	IC4PSC [1:0]	CC4S [1:0]	IC3F[3:0]	IC3PSC [1:0]	CC3S [1:0]																												
	Reset value																		0	0	0	0	0	0	0	0	0	0	0	0																						
0x20	<b>TIMx_CCER</b>	Reserved																	CC4NP	Reserved	CC4P	CC4E	CC3NP	Reserved	CC3P	CC3E	CC2NP	Reserved	CC2P	CC2E	CC1NP	Reserved	CC1P	CC1E																		
	Reset value																		0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0																		
0x24	<b>TIMx_CNT</b>	CNT[31:16] (TIM2 and TIM5 only, reserved on the other timers)																	CNT[15:0]																																	
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0																			
0x28	<b>TIMx_PSC</b>	Reserved																	PSC[15:0]																																	
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0																			



Table 56. TIM2 to TIM5 register map and reset values (continued)

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0														
0x2C	<b>TIMx_ARR</b>	ARR[31:16] (TIM2 and TIM5 only, reserved on the other timers)																ARR[15:0]																													
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0													
0x30	Reserved																																														
0x34	<b>TIMx_CCR1</b>	CCR1[31:16] (TIM2 and TIM5 only, reserved on the other timers)																CCR1[15:0]																													
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0													
0x38	<b>TIMx_CCR2</b>	CCR2[31:16] (TIM2 and TIM5 only, reserved on the other timers)																CCR2[15:0]																													
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0													
0x3C	<b>TIMx_CCR3</b>	CCR3[31:16] (TIM2 and TIM5 only, reserved on the other timers)																CCR3[15:0]																													
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0													
0x40	<b>TIMx_CCR4</b>	CCR4[31:16] (TIM2 and TIM5 only, reserved on the other timers)																CCR4[15:0]																													
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0													
0x44	Reserved																																														
0x48	<b>TIMx_DCR</b>	Reserved																DBL[4:0]				Reserved				DBA[4:0]																					
	Reset value																	0	0	0	0	0					0	0	0	0	0																
0x4C	<b>TIMx_DMAR</b>	Reserved																DMAB[15:0]																													
	Reset value																	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x50	<b>TIM2_OR</b>	Reserved																Reserved				ITR1_RMP		Reserved																							
	Reset value																					0	0																								
0x50	<b>TIM5_OR</b>	Reserved																Reserved								IT4_RMP		Reserved																			
	Reset value																									0	0																				

Refer to [Table 1 on page 38](#) for the register boundary addresses.

## 14 General-purpose timers (TIM9 to TIM11)

TIM12, TIM13 and TIM14 are not available in STM32F401xB/C and STM32F401xD/E.

### 14.1 TIM9/10/11 introduction

The TIM9/10/11 general-purpose timers consist of a 16-bit auto-reload counter driven by a programmable prescaler.

They may be used for a variety of purposes, including measuring the pulse lengths of input signals (input capture) or generating output waveforms (output compare, PWM).

Pulse lengths and waveform periods can be modulated from a few microseconds to several milliseconds using the timer prescaler and the RCC clock controller prescalers.

The TIM9/10/11 timers are completely independent, and do not share any resources. They can be synchronized together as described in [Section 14.3.12](#).

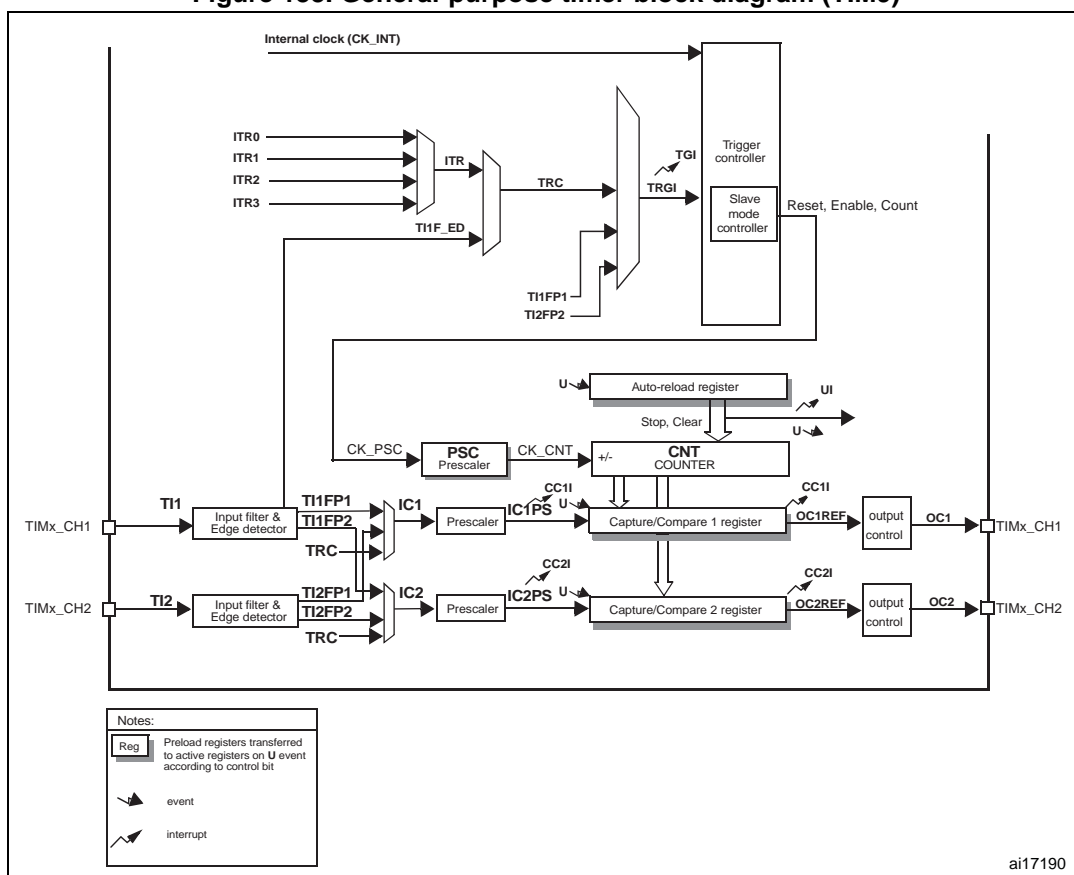
### 14.2 TIM9/10/11 main features

#### 14.2.1 TIM9 main features

The features of the TIM9 general-purpose timer include:

- 16-bit auto-reload upcounter
- 16-bit programmable prescaler used to divide the counter clock frequency by any factor between 1 and 65536 (can be changed “on the fly”)
- Up to 2 independent channels for:
  - Input capture
  - Output compare
  - PWM generation (edge-aligned mode)
  - One-pulse mode output
- Synchronization circuit to control the timer with external signals and to interconnect several timers together
- Interrupt generation on the following events:
  - Update: counter overflow, counter initialization (by software or internal trigger)
  - Trigger event (counter start, stop, initialization or count by internal trigger)
  - Input capture
  - Output compare

Figure 133. General-purpose timer block diagram (TIM9)



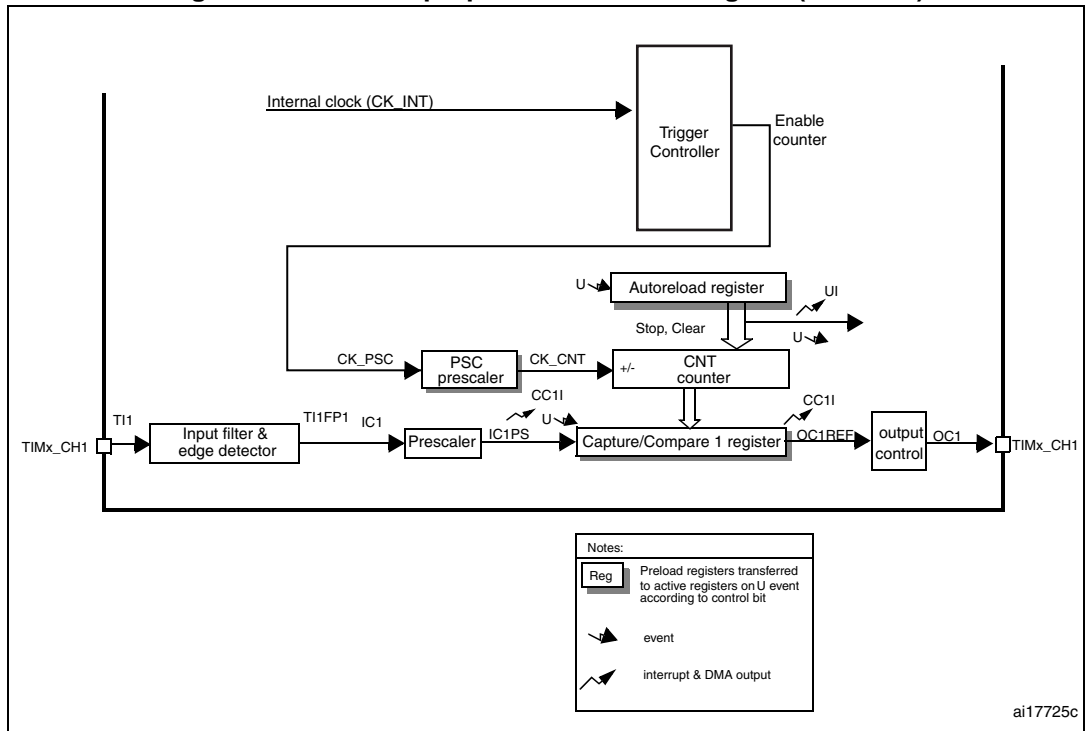
### 14.2.2 TIM10/TIM11 main features

The features of general-purpose timers TIM10/TIM11 include:

- 16-bit auto-reload upcounter
- 16-bit programmable prescaler used to divide the counter clock frequency by any factor between 1 and 65536 (can be changed “on the fly”)
- independent channel for:
  - Input capture
  - Output compare
  - PWM generation (edge-aligned mode)
  - One-pulse mode output
- Interrupt generation on the following events:
  - Update: counter overflow, counter initialization (by software)
  - Input capture
  - Output compare



Figure 134. General-purpose timer block diagram (TIM10/11)



## 14.3 TIM9 to TIM11 functional description

### 14.3.1 Time-base unit

The main block of the timer is a 16-bit counter with its related auto-reload register.

The counter clock can be divided by a prescaler.

The counter, the auto-reload register and the prescaler register can be written or read by software. This is true even when the counter is running.

The time-base unit includes:

- Counter register (TIMx\_CNT)
- Prescaler register (TIMx\_PSC)
- Auto-reload register (TIMx\_ARR)

The auto-reload register is preloaded. Writing to or reading from the auto-reload register accesses the preload register. The content of the preload register are transferred into the shadow register permanently or at each update event (UEV), depending on the auto-reload preload enable bit (ARPE) in TIMx\_CR1 register. The update event is sent when the counter reaches the overflow and if the UDIS bit equals 0 in the TIMx\_CR1 register. It can also be generated by software. The generation of the update event is described in details for each configuration.

The counter is clocked by the prescaler output CK\_CNT, which is enabled only when the counter enable bit (CEN) in TIMx\_CR1 register is set (refer also to the slave mode controller description to get more details on counter enabling).

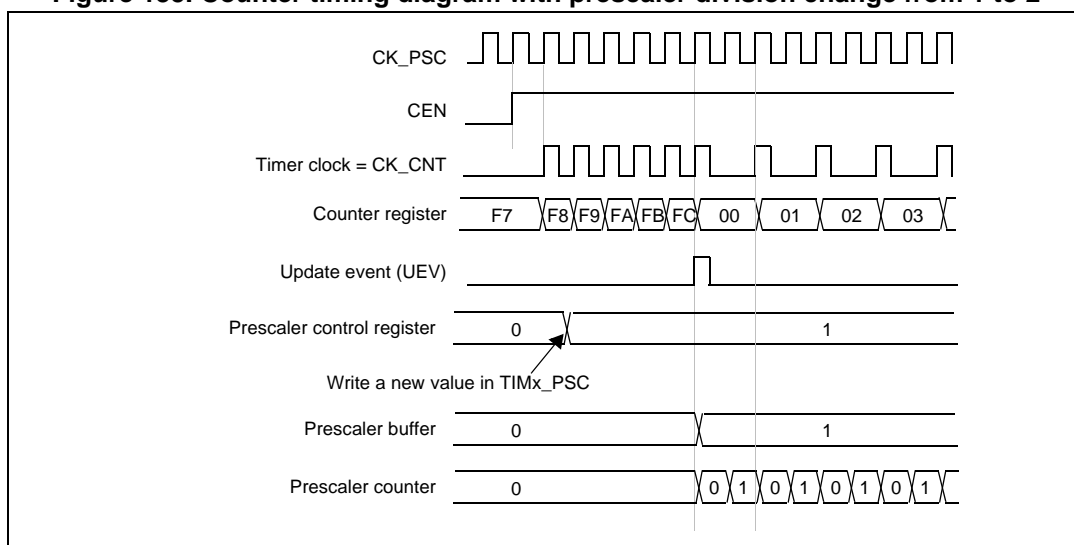
Note that the counter starts counting 1 clock cycle after setting the CEN bit in the TIMx\_CR1 register.

#### Prescaler description

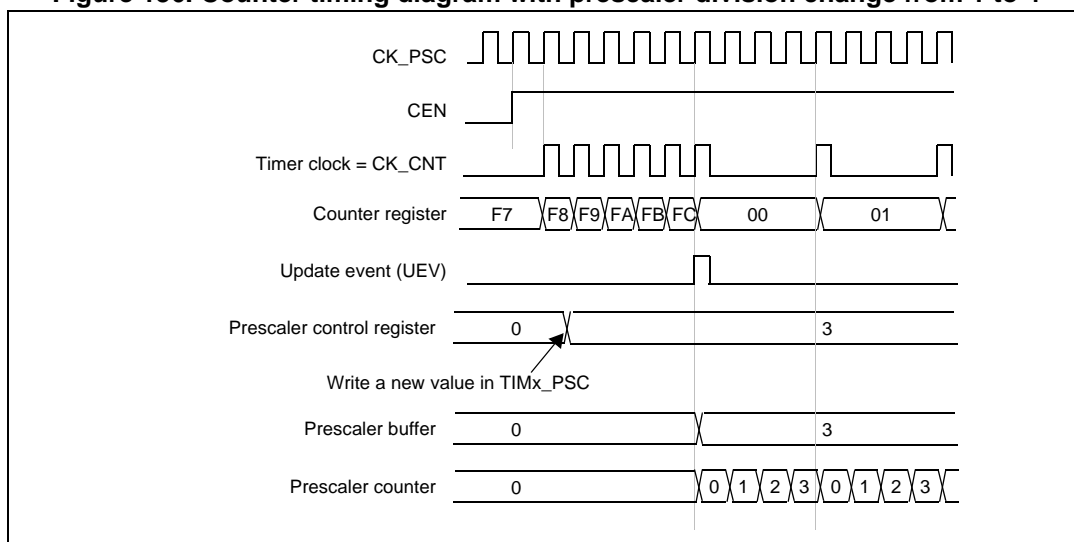
The prescaler can divide the counter clock frequency by any factor between 1 and 65536. It is based on a 16-bit counter controlled through a 16-bit register (in the TIMx\_PSC register). It can be changed on the fly as this control register is buffered. The new prescaler ratio is taken into account at the next update event.

*Figure 135* and *Figure 136* give some examples of the counter behavior when the prescaler ratio is changed on the fly.

**Figure 135. Counter timing diagram with prescaler division change from 1 to 2**



**Figure 136. Counter timing diagram with prescaler division change from 1 to 4**



### 14.3.2 Counter modes

#### Upcounting mode

In upcounting mode, the counter counts from 0 to the auto-reload value (content of the TIMx\_ARR register), then restarts from 0 and generates a counter overflow event.

Setting the UG bit in the TIMx\_EGR register (by software ) also generates an update event.

The UEV event can be disabled by software by setting the UDIS bit in the TIMx\_CR1 register. This is to avoid updating the shadow registers while writing new values in the preload registers. Then no update event occurs until the UDIS bit has been written to 0. However, the counter restarts from 0, as well as the counter of the prescaler (but the prescale rate does not change). In addition, if the URS bit (update request selection) in TIMx\_CR1 register is set, setting the UG bit generates an update event UEV but without

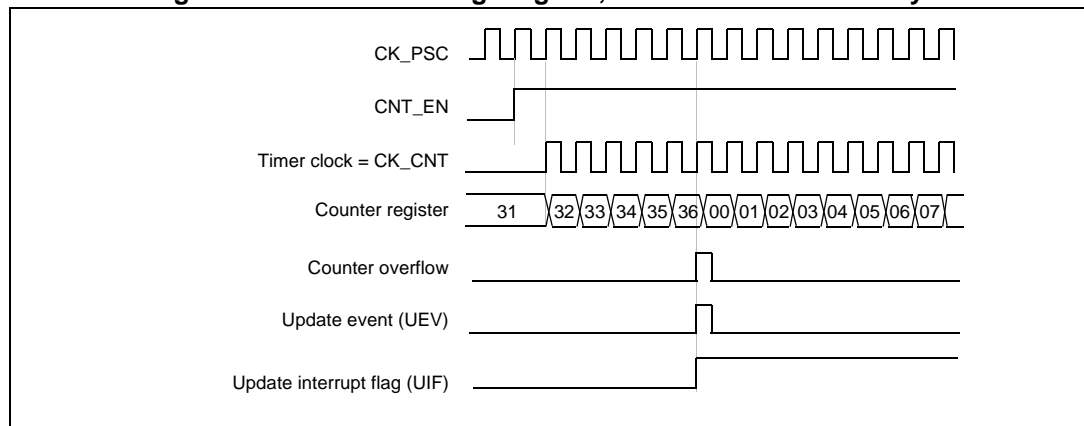
setting the UIF flag (thus no interrupt is sent). This is to avoid generating both update and capture interrupts when clearing the counter on the capture event.

When an update event occurs, all the registers are updated and the update flag (UIF bit in TIMx\_SR register) is set (depending on the URS bit):

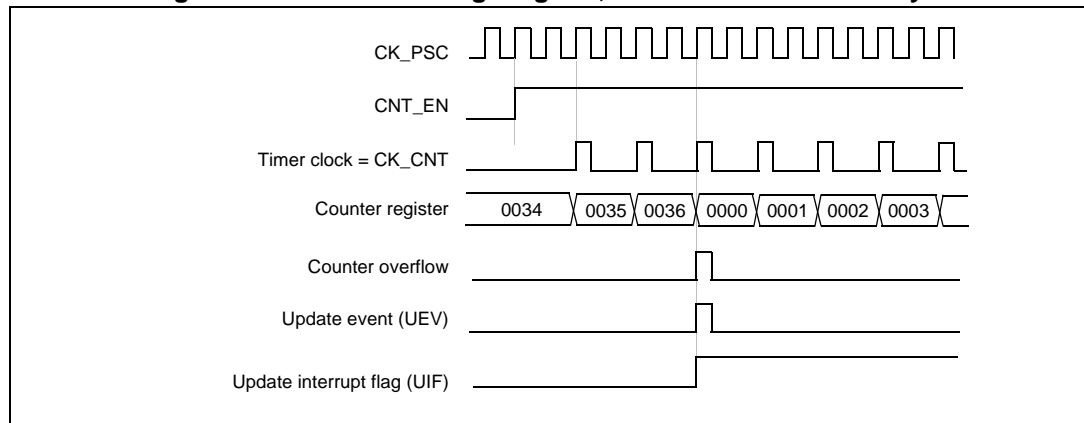
- The auto-reload shadow register is updated with the preload value (TIMx\_ARR),
- The buffer of the prescaler is reloaded with the preload value (content of the TIMx\_PSC register).

The following figures show some examples of the counter behavior for different clock frequencies when TIMx\_ARR=0x36.

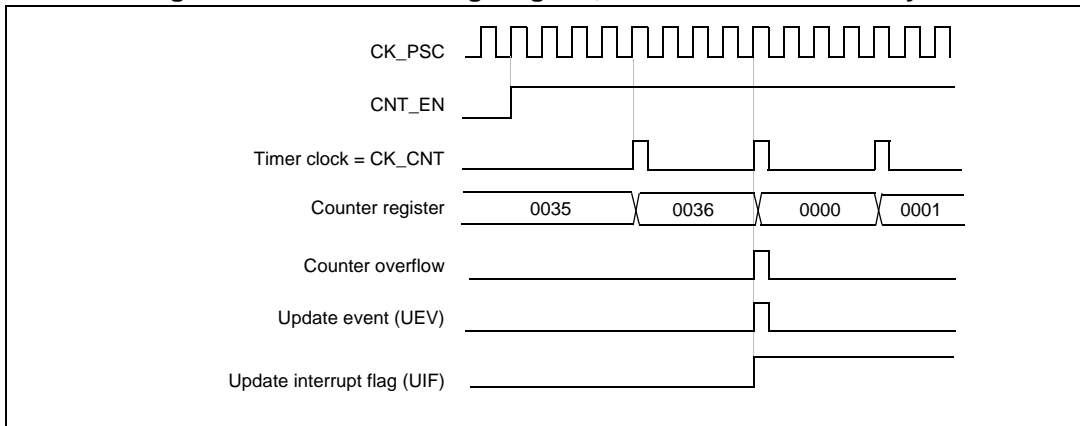
**Figure 137. Counter timing diagram, internal clock divided by 1**



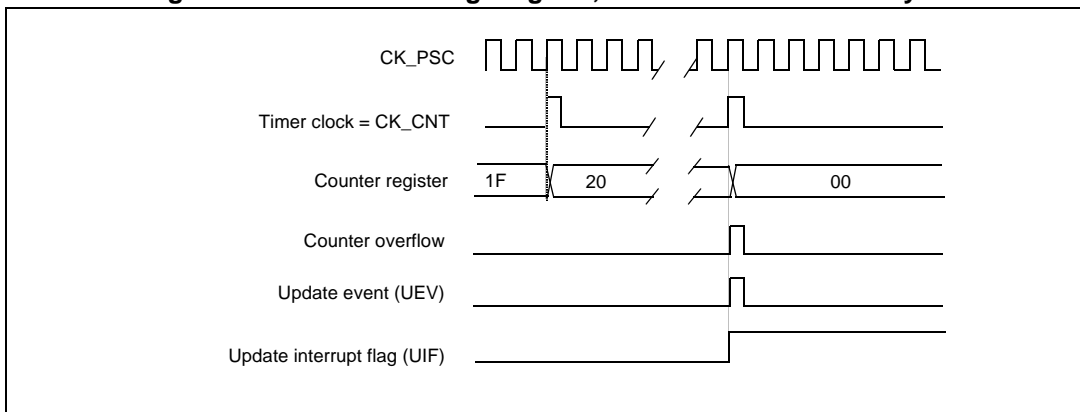
**Figure 138. Counter timing diagram, internal clock divided by 2**



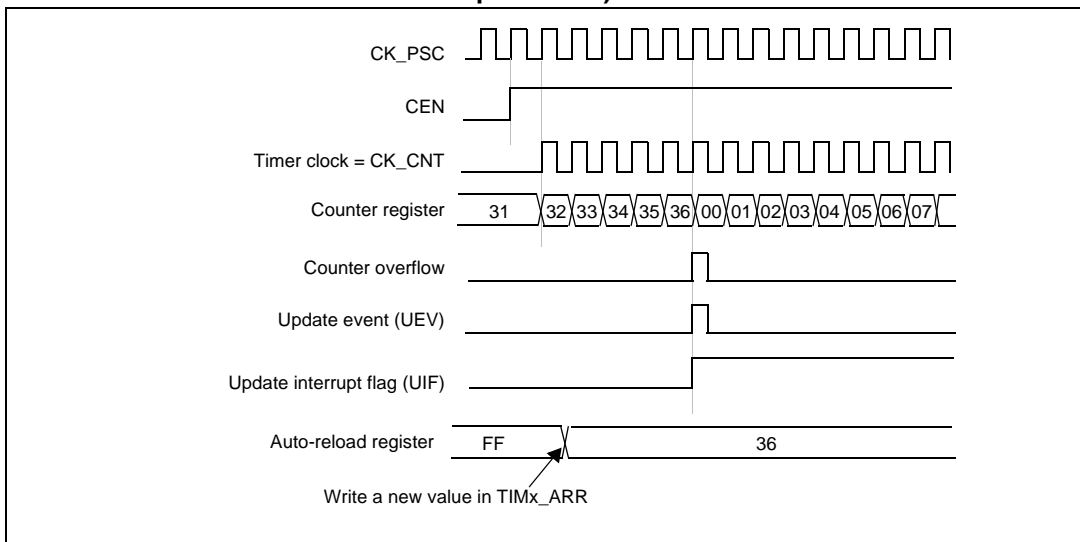
**Figure 139. Counter timing diagram, internal clock divided by 4**



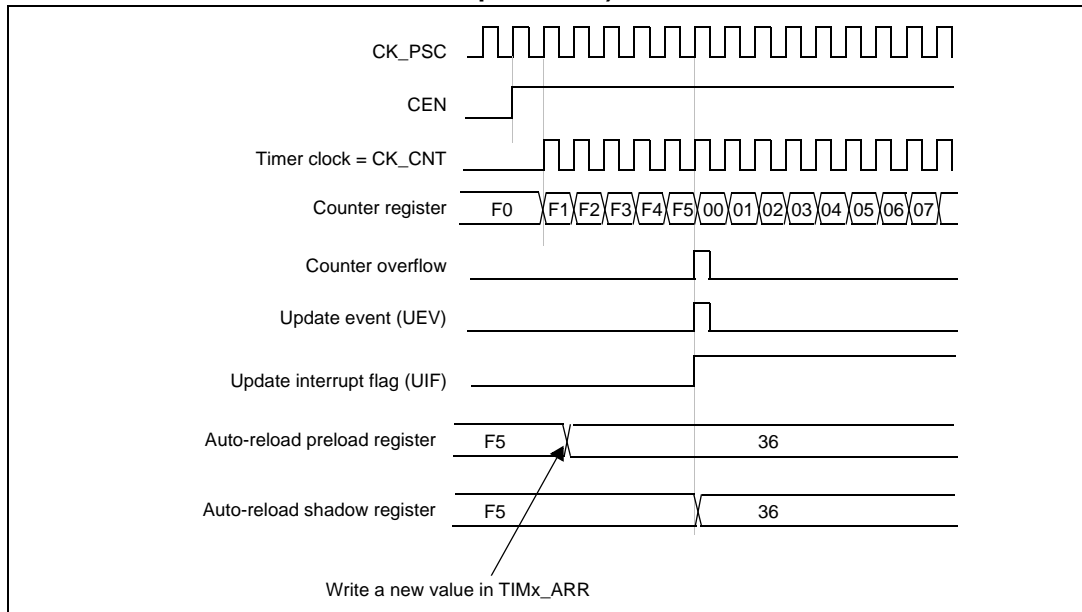
**Figure 140. Counter timing diagram, internal clock divided by N**



**Figure 141. Counter timing diagram, update event when ARPE=0 (TIMx\_ARR not preloaded)**



**Figure 142. Counter timing diagram, update event when ARPE=1 (TIMx\_ARR preloaded)**



### 14.3.3 Clock selection

The counter clock can be provided by the following clock sources:

- Internal clock (CK\_INT)
- External clock mode1 (for **TIM9**): external input pin (TIx)
- Internal trigger inputs (ITRx) (for **TIM9**): connecting the trigger output from another timer. Refer to [Section : Using one timer as prescaler for another timer](#) for more details.

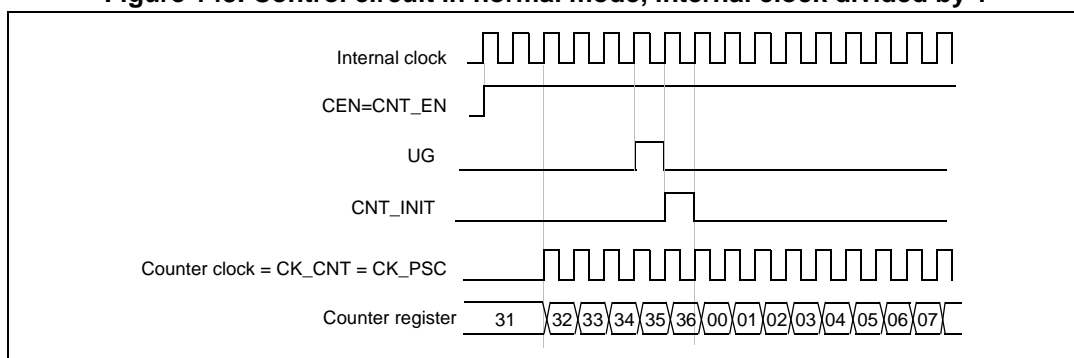
#### Internal clock source (CK\_INT)

The internal clock source is the default clock source for TIM10/TIM11.

For TIM9, the internal clock source is selected when the slave mode controller is disabled (SMS='000'). The CEN bit in the TIMx\_CR1 register and the UG bit in the TIMx\_EGR register are then used as control bits and can be changed only by software (except for UG which remains cleared). As soon as the CEN bit is programmed to 1, the prescaler is clocked by the internal clock CK\_INT.

*Figure 143* shows the behavior of the control circuit and the upcounter in normal mode, without prescaler.

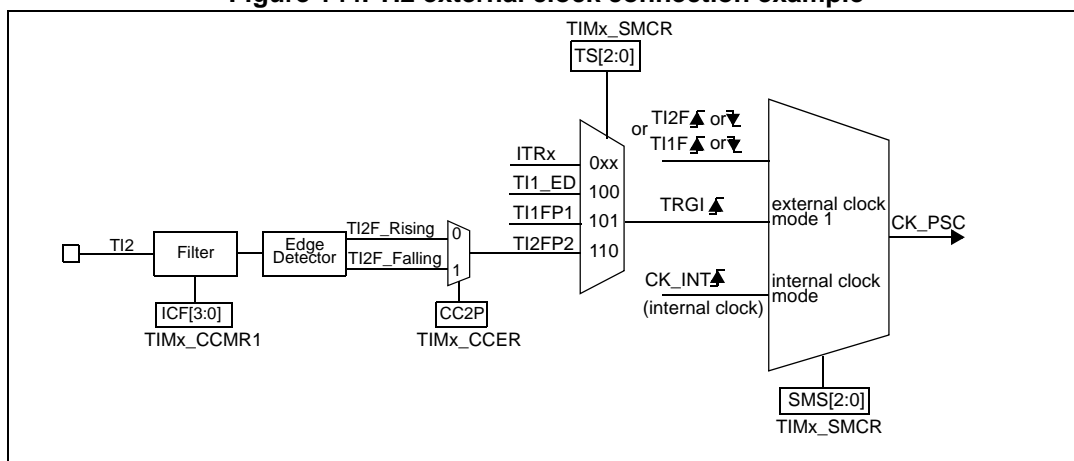
Figure 143. Control circuit in normal mode, internal clock divided by 1



External clock source mode 1(TIM9)

This mode is selected when SMS='111' in the TIMx\_SMCR register. The counter can count at each rising or falling edge on a selected input.

Figure 144. TI2 external clock connection example



For example, to configure the upcounter to count in response to a rising edge on the TI2 input, use the following procedure:

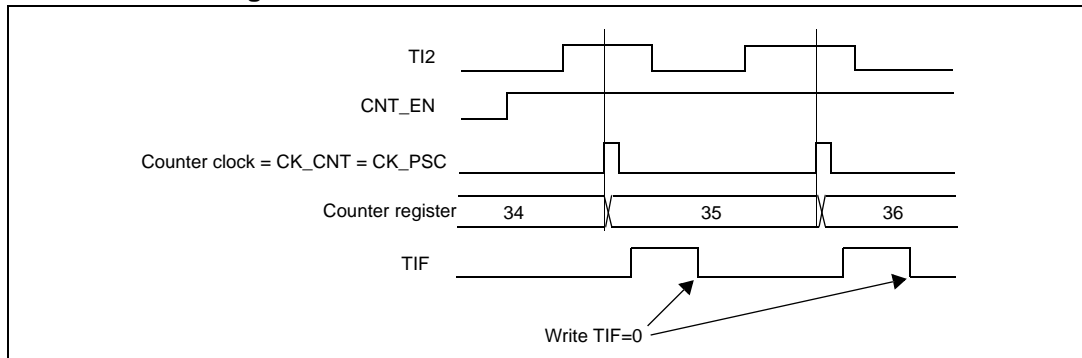
1. Configure channel 2 to detect rising edges on the TI2 input by writing CC2S = '01' in the TIMx\_CCMR1 register.
2. Configure the input filter duration by writing the IC2F[3:0] bits in the TIMx\_CCMR1 register (if no filter is needed, keep IC2F='0000').
3. Select the rising edge polarity by writing CC2P='0' and CC2NP='0' in the TIMx\_CCER register.
4. Configure the timer in external clock mode 1 by writing SMS='111' in the TIMx\_SMCR register.
5. Select TI2 as the trigger input source by writing TS='110' in the TIMx\_SMCR register.
6. Enable the counter by writing CEN='1' in the TIMx\_CR1 register.

Note: The capture prescaler is not used for triggering, so you don't need to configure it.

When a rising edge occurs on TI2, the counter counts once and the TIF flag is set.

The delay between the rising edge on TI2 and the actual clock of the counter is due to the resynchronization circuit on TI2 input.

Figure 145. Control circuit in external clock mode 1



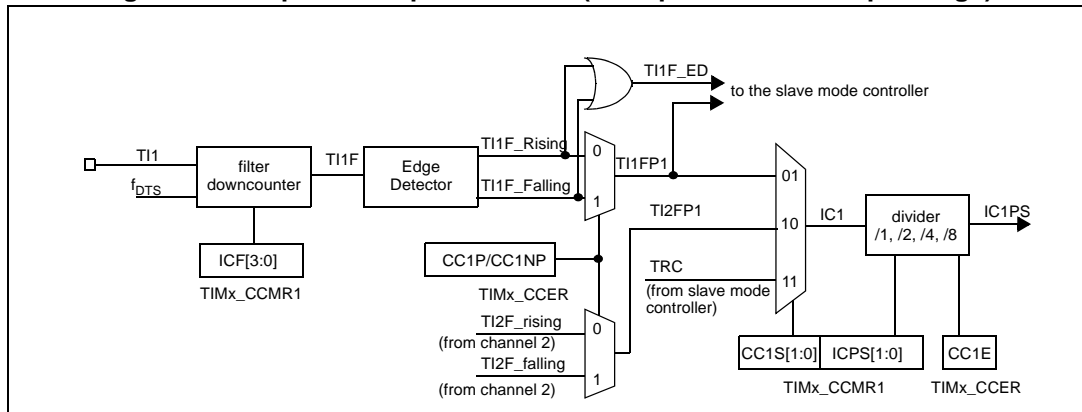
### 14.3.4 Capture/compare channels

Each Capture/Compare channel is built around a capture/compare register (including a shadow register), a input stage for capture (with digital filter, multiplexing and prescaler) and an output stage (with comparator and output control).

Figure 146 to Figure 148 give an overview of one capture/compare channel.

The input stage samples the corresponding T<sub>ix</sub> input to generate a filtered signal T<sub>ix</sub>F. Then, an edge detector with polarity selection generates a signal (T<sub>ix</sub>FP<sub>x</sub>) which can be used as trigger input by the slave mode controller or as the capture command. It is prescaled before the capture register (IC<sub>x</sub>PS).

Figure 146. Capture/compare channel (example: channel 1 input stage)



The output stage generates an intermediate waveform which is then used for reference: OC<sub>x</sub>Ref (active high). The polarity acts at the end of the chain.



Figure 147. Capture/compare channel 1 main circuit

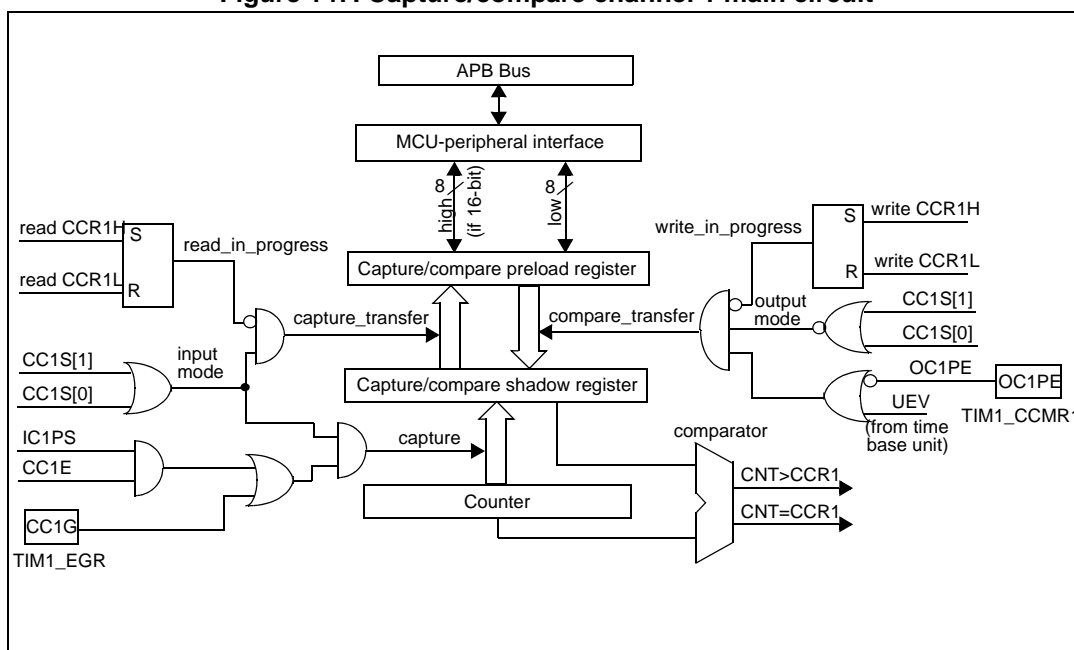
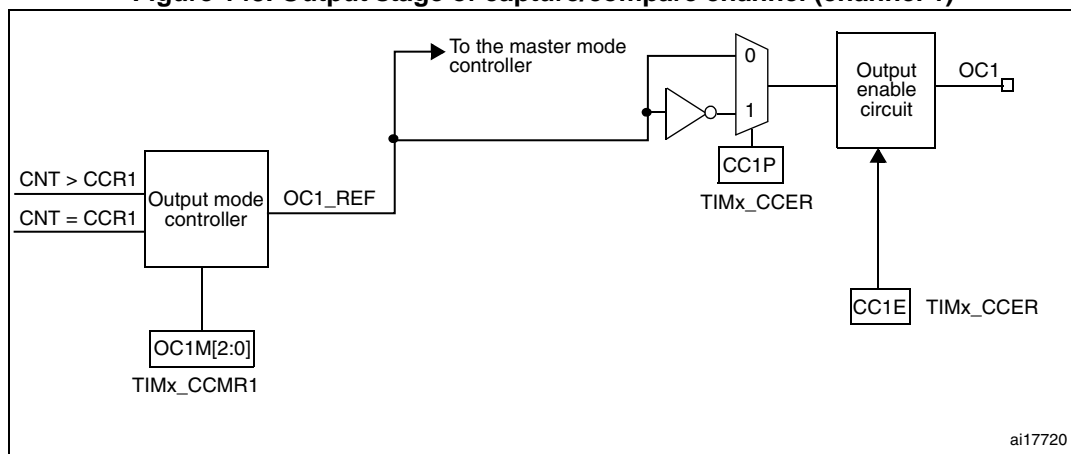


Figure 148. Output stage of capture/compare channel (channel 1)



The capture/compare block is made of one preload register and one shadow register. Write and read always access the preload register.

In capture mode, captures are actually done in the shadow register, which is copied into the preload register.

In compare mode, the content of the preload register is copied into the shadow register which is compared to the counter.

### 14.3.5 Input capture mode

In Input capture mode, the Capture/Compare Registers (TIMx\_CCRx) are used to latch the value of the counter after a transition detected by the corresponding ICx signal. When a capture occurs, the corresponding CCxIF flag (TIMx\_SR register) is set and an interrupt or a DMA request can be sent if they are enabled. If a capture occurs while the CCxIF flag was already high, then the over-capture flag CCxOF (TIMx\_SR register) is set. CCxIF can be

cleared by software by writing it to '0' or by reading the captured data stored in the TIMx\_CCRx register. CCxOF is cleared when you write it to '0'.

The following example shows how to capture the counter value in TIMx\_CCR1 when TI1 input rises. To do this, use the following procedure:

1. Select the active input: TIMx\_CCR1 must be linked to the TI1 input, so write the CC1S bits to '01' in the TIMx\_CCMR1 register. As soon as CC1S becomes different from '00', the channel is configured in input mode and the TIMx\_CCR1 register becomes read-only.
2. Program the input filter duration you need with respect to the signal you connect to the timer (by programming the ICxF bits in the TIMx\_CCMRx register if the input is one of the TIx inputs). Let's imagine that, when toggling, the input signal is not stable during at most 5 internal clock cycles. We must program a filter duration longer than these 5 clock cycles. We can validate a transition on TI1 when 8 consecutive samples with the new level have been detected (sampled at  $f_{DTS}$  frequency). Then write IC1F bits to '0011' in the TIMx\_CCMR1 register.
3. Select the edge of the active transition on the TI1 channel by programming CC1P and CC1NP bits to '00' in the TIMx\_CCER register (rising edge in this case).
4. Program the input prescaler. In our example, we wish the capture to be performed at each valid transition, so the prescaler is disabled (write IC1PS bits to '00' in the TIMx\_CCMR1 register).
5. Enable capture from the counter into the capture register by setting the CC1E bit in the TIMx\_CCER register.
6. If needed, enable the related interrupt request by setting the CC1IE bit in the TIMx\_DIER register.

When an input capture occurs:

- The TIMx\_CCR1 register gets the value of the counter on the active transition.
- CC1IF flag is set (interrupt flag). CC1OF is also set if at least two consecutive captures occurred whereas the flag was not cleared.
- An interrupt is generated depending on the CC1IE bit.

In order to handle the overcapture, it is recommended to read the data before the overcapture flag. This is to avoid missing an overcapture which could happen after reading the flag and before reading the data.

*Note:* IC interrupt requests can be generated by software by setting the corresponding CCxG bit in the TIMx\_EGR register.

### 14.3.6 PWM input mode (only for TIM9)

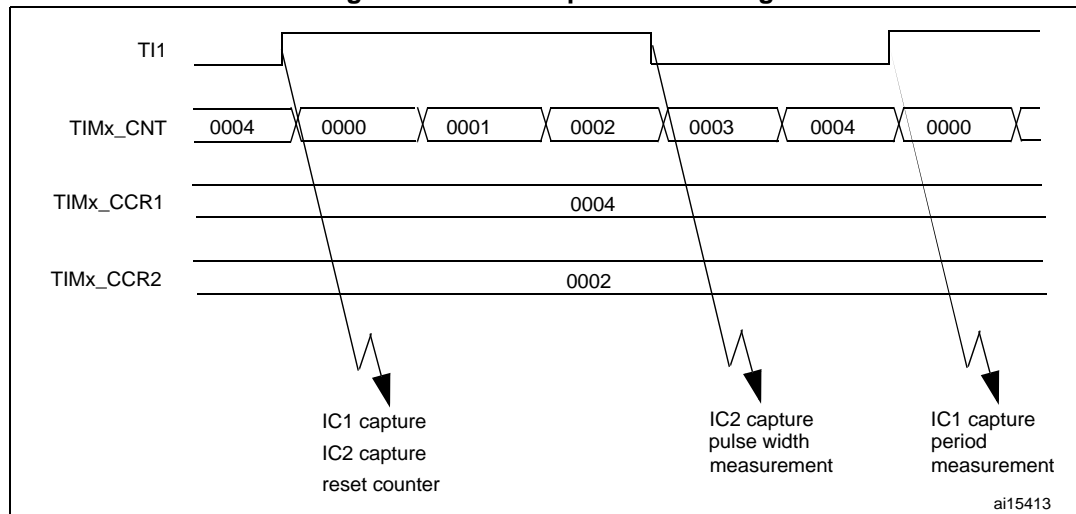
This mode is a particular case of input capture mode. The procedure is the same except:

- Two ICx signals are mapped on the same Tlx input.
- These 2 ICx signals are active on edges with opposite polarity.
- One of the two TlxFP signals is selected as trigger input and the slave mode controller is configured in reset mode.

For example, you can measure the period (in TIMx\_CCR1 register) and the duty cycle (in TIMx\_CCR2 register) of the PWM applied on TI1 using the following procedure (depending on CK\_INT frequency and prescaler value):

1. Select the active input for TIMx\_CCR1: write the CC1S bits to '01' in the TIMx\_CCMR1 register (TI1 selected).
2. Select the active polarity for TI1FP1 (used both for capture in TIMx\_CCR1 and counter clear): program the CC1P and CC1NP bits to '00' (active on rising edge).
3. Select the active input for TIMx\_CCR2: write the CC2S bits to '10' in the TIMx\_CCMR1 register (TI1 selected).
4. Select the active polarity for TI1FP2 (used for capture in TIMx\_CCR2): program the CC2P and CC2NP bits to '11' (active on falling edge).
5. Select the valid trigger input: write the TS bits to '101' in the TIMx\_SMCR register (TI1FP1 selected).
6. Configure the slave mode controller in reset mode: write the SMS bits to '100' in the TIMx\_SMCR register.
7. Enable the captures: write the CC1E and CC2E bits to '1' in the TIMx\_CCER register.

**Figure 149. PWM input mode timing**



1. The PWM input mode can be used only with the TIMx\_CH1/TIMx\_CH2 signals due to the fact that only TI1FP1 and TI2FP2 are connected to the slave mode controller.

### 14.3.7 Forced output mode

In output mode (CCxS bits = '00' in the TIMx\_CCMRx register), each output compare signal (OCxREF and then OCx) can be forced to active or inactive level directly by software, independently of any comparison between the output compare register and the counter.

To force an output compare signal (OCXREF/OCx) to its active level, you just need to write '101' in the OCxM bits in the corresponding TIMx\_CCMRx register. Thus OCXREF is forced high (OCxREF is always active high) and OCx get opposite value to CCxP polarity bit.

For example: CCxP='0' (OCx active high) => OCx is forced to high level.

The OCxREF signal can be forced low by writing the OCxM bits to '100' in the TIMx\_CCMRx register.

Anyway, the comparison between the TIMx\_CCRx shadow register and the counter is still performed and allows the flag to be set. Interrupt requests can be sent accordingly. This is described in the output compare mode section below.

### 14.3.8 Output compare mode

This function is used to control an output waveform or indicating when a period of time has elapsed.

When a match is found between the capture/compare register and the counter, the output compare function:

1. Assigns the corresponding output pin to a programmable value defined by the output compare mode (OCxM bits in the TIMx\_CCMRx register) and the output polarity (CCxP bit in the TIMx\_CCER register). The output pin can keep its level (OCxM='000'), be set active (OCxM='001'), be set inactive (OCxM='010') or can toggle (OCxM='011') on match.
2. Sets a flag in the interrupt status register (CCxIF bit in the TIMx\_SR register).
3. Generates an interrupt if the corresponding interrupt mask is set (CCxIE bit in the TIMx\_DIER register).

The TIMx\_CCRx registers can be programmed with or without preload registers using the OCxPE bit in the TIMx\_CCMRx register.

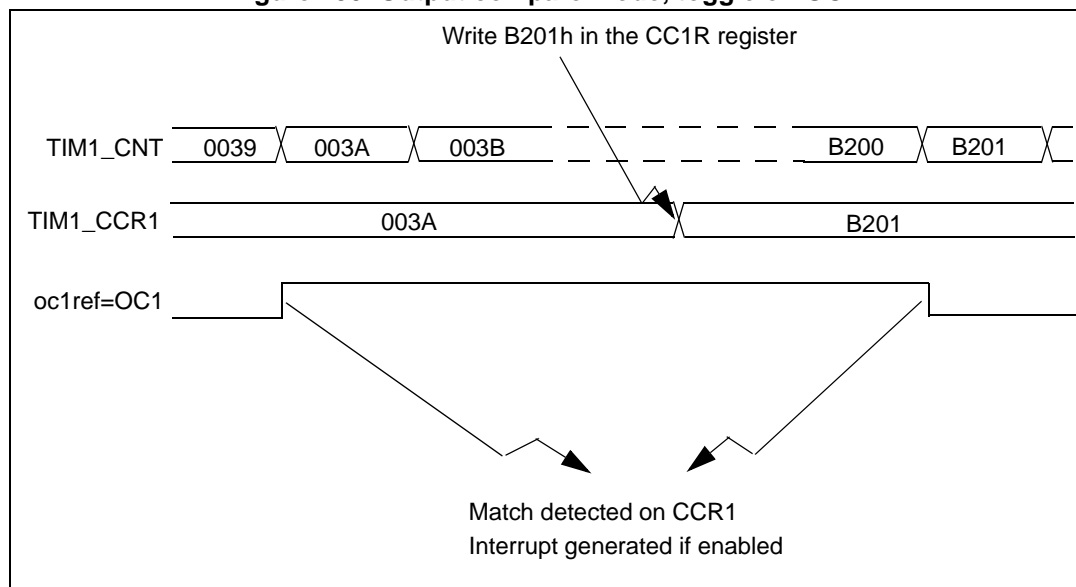
In output compare mode, the update event UEV has no effect on OCxREF and OCx output. The timing resolution is one count of the counter. Output compare mode can also be used to output a single pulse (in One-pulse mode).

Procedure:

1. Select the counter clock (internal, external, prescaler).
2. Write the desired data in the TIMx\_ARR and TIMx\_CCRx registers.
3. Set the CCxIE bit if an interrupt request is to be generated.
4. Select the output mode. For example:
  - Write OCxM = '011' to toggle OCx output pin when CNT matches CCRx
  - Write OCxPE = '0' to disable preload register
  - Write CCxP = '0' to select active high polarity
  - Write CCxE = '1' to enable the output
5. Enable the counter by setting the CEN bit in the TIMx\_CR1 register.

The TIMx\_CCRx register can be updated at any time by software to control the output waveform, provided that the preload register is not enabled (OCxPE='0', else TIMx\_CCRx shadow register is updated only at the next update event UEV). An example is given in [Figure 150](#).

**Figure 150. Output compare mode, toggle on OC1.**



### 14.3.9 PWM mode

Pulse Width Modulation mode allows you to generate a signal with a frequency determined by the value of the TIMx\_ARR register and a duty cycle determined by the value of the TIMx\_CCRx register.

The PWM mode can be selected independently on each channel (one PWM per OCx output) by writing '110' (PWM mode 1) or '111' (PWM mode 2) in the OCxM bits in the TIMx\_CCMRx register. You must enable the corresponding preload register by setting the OCxPE bit in the TIMx\_CCMRx register, and eventually the auto-reload preload register (in upcounting or center-aligned modes) by setting the ARPE bit in the TIMx\_CR1 register.

As the preload registers are transferred to the shadow registers only when an update event occurs, before starting the counter, you have to initialize all the registers by setting the UG bit in the TIMx\_EGR register.

The OCx polarity is software programmable using the CCxP bit in the TIMx\_CCER register. It can be programmed as active high or active low. The OCx output is enabled by the CCxE bit in the TIMx\_CCER register. Refer to the TIMx\_CCERx register description for more details.

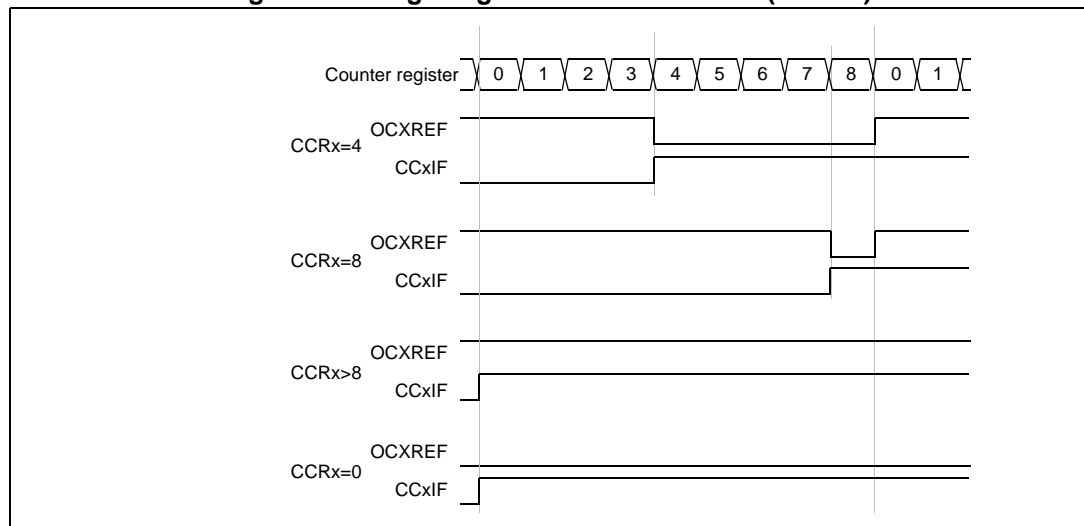
In PWM mode (1 or 2), TIMx\_CNT and TIMx\_CCRx are always compared to determine whether  $TIMx\_CNT \leq TIMx\_CCRx$ .

The timer is able to generate PWM in edge-aligned mode only since the counter is upcounting.

### PWM edge-aligned mode

In the following example, we consider PWM mode 1. The reference PWM signal OCxREF is high as long as TIMx\_CNT < TIMx\_CCRx else it becomes low. If the compare value in TIMx\_CCRx is greater than the auto-reload value (in TIMx\_ARR) then OCxREF is held at '1'. If the compare value is 0 then OCxRef is held at '0'. *Figure 151* shows some edge-aligned PWM waveforms in an example where TIMx\_ARR=8.

**Figure 151. Edge-aligned PWM waveforms (ARR=8)**



### 14.3.10 One-pulse mode

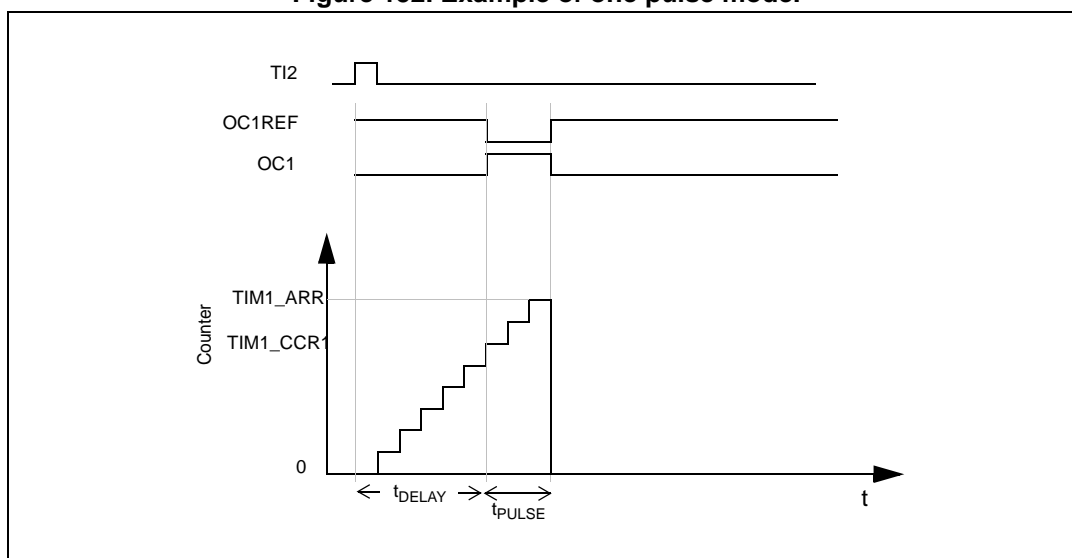
One-pulse mode (OPM) is a particular case of the previous modes. It allows the counter to be started in response to a stimulus and to generate a pulse with a programmable length after a programmable delay.

Starting the counter can be controlled through the slave mode controller. Generating the waveform can be done in output compare mode or PWM mode. You select One-pulse mode by setting the OPM bit in the TIMx\_CR1 register. This makes the counter stop automatically at the next update event UEV.

A pulse can be correctly generated only if the compare value is different from the counter initial value. Before starting (when the timer is waiting for the trigger), the configuration must be as follows:

$$CNT < CCRx \leq ARR \text{ (in particular, } 0 < CCRx)$$

Figure 152. Example of one pulse mode.



For example you may want to generate a positive pulse on OC1 with a length of  $t_{PULSE}$  and after a delay of  $t_{DELAY}$  as soon as a positive edge is detected on the TI2 input pin.

Use TI2FP2 as trigger 1:

1. Map TI2FP2 to TI2 by writing  $CC2S='01'$  in the  $TIMx\_CCMR1$  register.
2. TI2FP2 must detect a rising edge, write  $CC2P='0'$  and  $CC2NP = '0'$  in the  $TIMx\_CCER$  register.
3. Configure TI2FP2 as trigger for the slave mode controller (TRGI) by writing  $TS='110'$  in the  $TIMx\_SMCR$  register.
4. TI2FP2 is used to start the counter by writing  $SMS$  to  $'110'$  in the  $TIMx\_SMCR$  register (trigger mode).

The OPM waveform is defined by writing the compare registers (taking into account the clock frequency and the counter prescaler).

- The  $t_{DELAY}$  is defined by the value written in the  $TIMx\_CCR1$  register.
- The  $t_{PULSE}$  is defined by the difference between the auto-reload value and the compare value ( $TIMx\_ARR - TIMx\_CCR1$ ).
- Let's say you want to build a waveform with a transition from '0' to '1' when a compare match occurs and a transition from '1' to '0' when the counter reaches the auto-reload value. To do this you enable PWM mode 2 by writing  $OC1M='111'$  in the  $TIMx\_CCMR1$  register. You can optionally enable the preload registers by writing  $OC1PE='1'$  in the  $TIMx\_CCMR1$  register and  $ARPE$  in the  $TIMx\_CR1$  register. In this case you have to write the compare value in the  $TIMx\_CCR1$  register, the auto-reload value in the  $TIMx\_ARR$  register, generate an update by setting the  $UG$  bit and wait for external trigger event on TI2.  $CC1P$  is written to  $'0'$  in this example.

You only want 1 pulse (Single mode), so you write '1' in the  $OPM$  bit in the  $TIMx\_CR1$  register to stop the counter at the next update event (when the counter rolls over from the auto-reload value back to 0). When  $OPM$  bit in the  $TIMx\_CR1$  register is set to '0', so the Repetitive Mode is selected.

**Particular case: OCx fast enable**

In One-pulse mode, the edge detection on TIx input set the CEN bit which enables the counter. Then the comparison between the counter and the compare value makes the output toggle. But several clock cycles are needed for these operations and it limits the minimum delay  $t_{DELAY\ min}$  we can get.

If you want to output a waveform with the minimum delay, you can set the OCxFE bit in the TIMx\_CCMRx register. Then OCxRef (and OCx) are forced in response to the stimulus, without taking in account the comparison. Its new level is the same as if a compare match had occurred. OCxFE acts only if the channel is configured in PWM1 or PWM2 mode.

### 14.3.11 TIM9 external trigger synchronization

The TIM9 timer can be synchronized with an external trigger in several modes: Reset mode, Gated mode and Trigger mode.

#### Slave mode: Reset mode

The counter and its prescaler can be reinitialized in response to an event on a trigger input. Moreover, if the URS bit from the TIMx\_CR1 register is low, an update event UEV is generated. Then all the preloaded registers (TIMx\_ARR, TIMx\_CCRx) are updated.

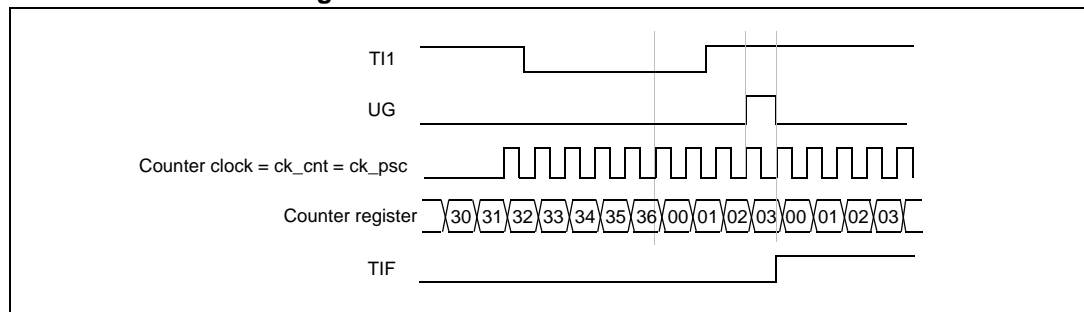
In the following example, the upcounter is cleared in response to a rising edge on TI1 input:

1. Configure the channel 1 to detect rising edges on TI1. Configure the input filter duration (in this example, we don't need any filter, so we keep IC1F='0000'). The capture prescaler is not used for triggering, so you don't need to configure it. The CC1S bits select the input capture source only, CC1S = '01' in the TIMx\_CCMR1 register. Program CC1P and CC1NP to '00' in TIMx\_CCER register to validate the polarity (and detect rising edges only).
2. Configure the timer in reset mode by writing SMS='100' in TIMx\_SMCR register. Select TI1 as the input source by writing TS='101' in TIMx\_SMCR register.
3. Start the counter by writing CEN='1' in the TIMx\_CR1 register.

The counter starts counting on the internal clock, then behaves normally until TI1 rising edge. When TI1 rises, the counter is cleared and restarts from 0. In the meantime, the trigger flag is set (TIF bit in the TIMx\_SR register) and an interrupt request can be sent if enabled (depending on the TIE bit in TIMx\_DIER register).

The following figure shows this behavior when the auto-reload register TIMx\_ARR=0x36. The delay between the rising edge on TI1 and the actual reset of the counter is due to the resynchronization circuit on TI1 input.

Figure 153. Control circuit in reset mode





**Slave mode: Gated mode**

The counter can be enabled depending on the level of a selected input.

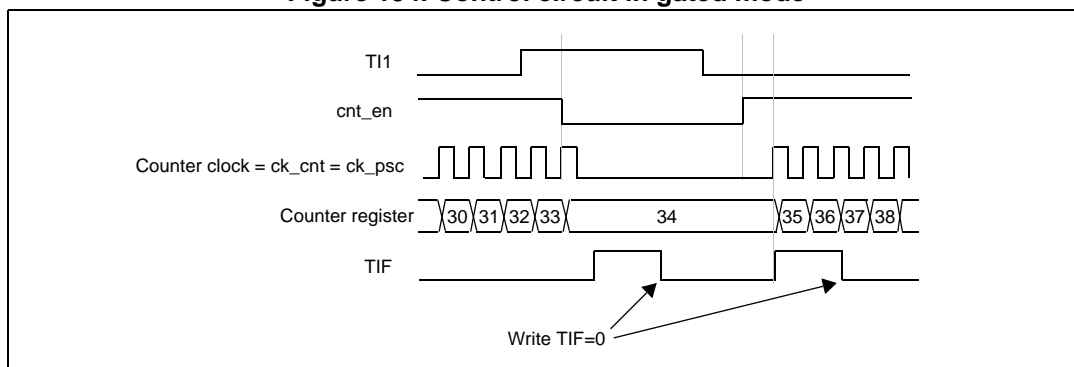
In the following example, the upcounter counts only when TI1 input is low:

1. Configure the channel 1 to detect low levels on TI1. Configure the input filter duration (in this example, we don't need any filter, so we keep IC1F='0000'). The capture prescaler is not used for triggering, so you don't need to configure it. The CC1S bits select the input capture source only, CC1S='01' in TIMx\_CCMR1 register. Program CC1P='1' and CC1NP='0' in TIMx\_CCER register to validate the polarity (and detect low level only).
2. Configure the timer in gated mode by writing SMS='101' in TIMx\_SMCR register. Select TI1 as the input source by writing TS='101' in TIMx\_SMCR register.
3. Enable the counter by writing CEN='1' in the TIMx\_CR1 register (in gated mode, the counter doesn't start if CEN='0', whatever is the trigger input level).

The counter starts counting on the internal clock as long as TI1 is low and stops as soon as TI1 becomes high. The TIF flag in the TIMx\_SR register is set both when the counter starts or stops.

The delay between the rising edge on TI1 and the actual stop of the counter is due to the resynchronization circuit on TI1 input.

**Figure 154. Control circuit in gated mode**



**Slave mode: Trigger mode**

The counter can start in response to an event on a selected input.

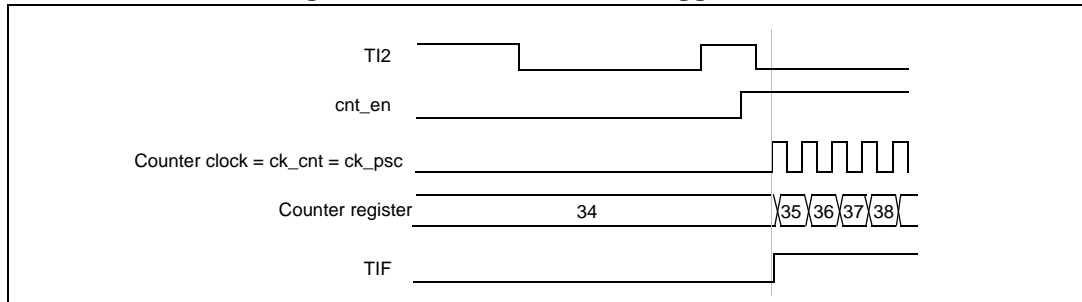
In the following example, the upcounter starts in response to a rising edge on TI2 input:

1. Configure the channel 2 to detect rising edges on TI2. Configure the input filter duration (in this example, we don't need any filter, so we keep IC2F='0000'). The capture prescaler is not used for triggering, so you don't need to configure it. The CC2S bits are configured to select the input capture source only, CC2S='01' in TIMx\_CCMR1 register. Program CC2P='1' and CC2NP='0' in TIMx\_CCER register to validate the polarity (and detect low level only).
2. Configure the timer in trigger mode by writing SMS='110' in TIMx\_SMCR register. Select TI2 as the input source by writing TS='110' in TIMx\_SMCR register.

When a rising edge occurs on TI2, the counter starts counting on the internal clock and the TIF flag is set.

The delay between the rising edge on TI2 and the actual start of the counter is due to the resynchronization circuit on TI2 input.

**Figure 155. Control circuit in trigger mode**



**14.3.12 Timer synchronization (TIM9)**

The TIM timers are linked together internally for timer synchronization or chaining. Refer to [Section 13.3.15: Timer synchronization on page 341](#) for details.

**14.3.13 Debug mode**

When the microcontroller enters debug mode (Cortex<sup>®</sup>-M4 with FPU core halted), the TIMx counter either continues to work normally or stops, depending on DBG\_TIMx\_STOP configuration bit in DBG module. For more details, refer to [Section 23.16.2: Debug support for timers, watchdog and I2C](#).

## 14.4 TIM9 registers

Refer to [Section 1.1](#) for a list of abbreviations used in register descriptions.

The peripheral registers have to be written by half-words (16 bits) or words (32 bits). Read accesses can be done by bytes (8 bits), half-words (16 bits) or words (32 bits).

### 14.4.1 TIM9 control register 1 (TIMx\_CR1)

Address offset: 0x00

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0		
Reserved						CKD[1:0]			ARPE	Reserved				OPM	URS	UDIS	CEN
						rw	rw	rw					rw	rw	rw	rw	

Bits 15:10 Reserved, must be kept at reset value.

Bits 9:8 **CKD**: Clock division

This bit-field indicates the division ratio between the timer clock (CK\_INT) frequency and sampling clock used by the digital filters (Tix),

- 00:  $t_{DTS} = t_{CK\_INT}$
- 01:  $t_{DTS} = 2 \times t_{CK\_INT}$
- 10:  $t_{DTS} = 4 \times t_{CK\_INT}$
- 11: Reserved

Bit 7 **ARPE**: Auto-reload preload enable

- 0: TIMx\_ARR register is not buffered.
- 1: TIMx\_ARR register is buffered.

Bits 6:4 Reserved, must be kept at reset value.

Bit 3 **OPM**: One-pulse mode

- 0: Counter is not stopped on the update event
- 1: Counter stops counting on the next update event (clearing the CEN bit).

Bit 2 **URS**: Update request source

This bit is set and cleared by software to select the UEV event sources.

- 0: Any of the following events generates an update interrupt if enabled:
  - Counter overflow
  - Setting the UG bit
- 1: Only counter overflow generates an update interrupt if enabled.

Bit 1 **UDIS**: Update disable

This bit is set and cleared by software to enable/disable update event (UEV) generation.

- 0: UEV enabled. An UEV is generated by one of the following events:
  - Counter overflow
  - Setting the UG bit

Buffered registers are then loaded with their preload values.

- 1: UEV disabled. No UEV is generated, shadow registers keep their value (ARR, PSC, CCRx). The counter and the prescaler are reinitialized if the UG bit is set.

Bit 0 **CEN**: Counter enable

- 0: Counter disabled
- 1: Counter enabled

CEN is cleared automatically in one-pulse mode, when an update event occurs.

**14.4.2 TIM9 slave mode control register (TIMx\_SMCR)**

Address offset: 0x08

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
Reserved								MSM	TS[2:0]				Res.	SMS[2:0]		
								rw	rw	rw	rw		rw	rw	rw	

Bits 15:8 Reserved, must be kept at reset value.

Bit 7 **MSM**: Master/Slave mode

0: No action

1: The effect of an event on the trigger input (TRGI) is delayed to allow a perfect synchronization between the current timer and its slaves (through TRGO). It is useful in order to synchronize several timers on a single external event.

Bits 6:4 **TS**: Trigger selection

This bitfield selects the trigger input to be used to synchronize the counter.

000: Internal Trigger 0 (ITR0)

001: Internal Trigger 1 (ITR1)

010: Internal Trigger 2 (ITR2)

011: Internal Trigger 3 (ITR3)

100: TI1 Edge Detector (TI1F\_ED)

101: Filtered Timer Input 1 (TI1FP1)

110: Filtered Timer Input 2 (TI2FP2)

111: Reserved.

See [Table 57: TIMx internal trigger connection on page 392](#) for more details on the meaning of ITRx for each timer.

*Note: These bits must be changed only when they are not used (e.g. when SMS='000') to avoid wrong edge detections at the transition.*

Bit 3 Reserved, must be kept at reset value.

Bits 2:0 **SMS**: Slave mode selection

When external signals are selected, the active edge of the trigger signal (TRGI) is linked to the polarity selected on the external input (see Input control register and Control register descriptions).

000: Slave mode disabled - if CEN = 1 then the prescaler is clocked directly by the internal clock

001: Reserved

010: Reserved

011: Reserved

100: Reset mode - Rising edge of the selected trigger input (TRGI) reinitializes the counter and generates an update of the registers

101: Gated mode - The counter clock is enabled when the trigger input (TRGI) is high. The counter stops (but is not reset) as soon as the trigger becomes low. Counter starts and stops are both controlled

110: Trigger mode - The counter starts on a rising edge of the trigger TRGI (but it is not reset). Only the start of the counter is controlled

111: External clock mode 1 - Rising edges of the selected trigger (TRGI) clock the counter

*Note: The Gated mode must not be used if TI1F\_ED is selected as the trigger input (TS='100'). Indeed, TI1F\_ED outputs 1 pulse for each transition on TI1F, whereas the Gated mode checks the level of the trigger signal.*

Table 57. TIMx internal trigger connection

Slave TIM	ITR0 (TS = '000')	ITR1 (TS = '001')	ITR2 (TS = '010')	ITR3 (TS = '011')
TIM9	TIM2_TRGO	TIM3_TRGO	TIM10_OC	TIM11_OC

### 14.4.3 TIM9 Interrupt enable register (TIMx\_DIER)

Address offset: 0x0C

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved									TIE	Res			CC2IE	CC1IE	UIE
									rw				rw	rw	rw

Bits 15:7 Reserved, must be kept at reset value.

Bit 6 **TIE**: Trigger interrupt enable  
 0: Trigger interrupt disabled.  
 1: Trigger interrupt enabled.

Bits 5:3 Reserved, must be kept at reset value.

Bit 2 **CC2IE**: Capture/Compare 2 interrupt enable  
 0: CC2 interrupt disabled.  
 1: CC2 interrupt enabled.

Bit 1 **CC1IE**: Capture/Compare 1 interrupt enable  
 0: CC1 interrupt disabled.  
 1: CC1 interrupt enabled.

Bit 0 **UIE**: Update interrupt enable  
 0: Update interrupt disabled.  
 1: Update interrupt enabled.

### 14.4.4 TIM9 status register (TIMx\_SR)

Address offset: 0x10

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved					CC2OF	CC1OF	Reserved		TIF	Reserved			CC2IF	CC1IF	UIF
					rc_w0	rc_w0			rc_w0				rc_w0	rc_w0	rc_w0

Bits 15:11 Reserved, must be kept at reset value.

Bit 10 **CC2OF**: Capture/compare 2 overcapture flag  
refer to CC1OF description

Bit 9 **CC1OF**: Capture/Compare 1 overcapture flag

This flag is set by hardware only when the corresponding channel is configured in input capture mode. It is cleared by software by writing it to '0'.

0: No overcapture has been detected.

1: The counter value has been captured in TIMx\_CCR1 register while CC1IF flag was already set

Bits 8:7 Reserved, must be kept at reset value.

Bit 6 **TIF**: Trigger interrupt flag

This flag is set by hardware on trigger event (active edge detected on TRGI input when the slave mode controller is enabled in all modes but gated mode. It is set when the counter starts or stops when gated mode is selected. It is cleared by software.

0: No trigger event occurred.

1: Trigger interrupt pending.

Bits 5:3 Reserved, must be kept at reset value.

- Bit 2 **CC2IF**: Capture/Compare 2 interrupt flag  
refer to CC1IF description
- Bit 1 **CC1IF**: Capture/compare 1 interrupt flag  
**If channel CC1 is configured as output:**  
 This flag is set by hardware when the counter matches the compare value. It is cleared by software.  
 0: No match.  
 1: The content of the counter TIMx\_CNT matches the content of the TIMx\_CCR1 register. When the contents of TIMx\_CCR1 are greater than the contents of TIMx\_ARR, the CC1IF bit goes high on the counter overflow.  
**If channel CC1 is configured as input:**  
 This bit is set by hardware on a capture. It is cleared by software or by reading the TIMx\_CCR1 register.  
 0: No input capture occurred.  
 1: The counter value has been captured in TIMx\_CCR1 register (an edge has been detected on IC1 which matches the selected polarity).
- Bit 0 **UIF**: Update interrupt flag  
 This bit is set by hardware on an update event. It is cleared by software.  
 0: No update occurred.  
 1: Update interrupt pending. This bit is set by hardware when the registers are updated:
  - At overflow and if UDIS='0' in the TIMx\_CR1 register.
  - When CNT is reinitialized by software using the UG bit in TIMx\_EGR register, if URS='0' and UDIS='0' in the TIMx\_CR1 register.
  - When CNT is reinitialized by a trigger event (refer to the synchro control register description), if URS='0' and UDIS='0' in the TIMx\_CR1 register.

### 14.4.5 TIM9 event generation register (TIMx\_EGR)

Address offset: 0x14

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved									TG	Reserved			CC2G	CC1G	UG
Reserved									w	Reserved			w	w	w

Bits 15:7 Reserved, must be kept at reset value.

Bit 6 **TG**: Trigger generation

This bit is set by software in order to generate an event, it is automatically cleared by hardware.

0: No action

1: The TIF flag is set in the TIMx\_SR register. Related interrupt can occur if enabled

Bits 5:3 Reserved, must be kept at reset value.

Bit 2 **CC2G**: Capture/compare 2 generation  
refer to CC1G description

Bit 1 **CC1G**: Capture/compare 1 generation

This bit is set by software to generate an event, it is automatically cleared by hardware.

0: No action

1: A capture/compare event is generated on channel 1:

**If channel CC1 is configured as output:**

the CC1IF flag is set, the corresponding interrupt is sent if enabled.

**If channel CC1 is configured as input:**

The current counter value is captured in the TIMx\_CCR1 register. The CC1IF flag is set, the corresponding interrupt is sent if enabled. The CC1OF flag is set if the CC1IF flag was already high.

Bit 0 **UG**: Update generation

This bit can be set by software, it is automatically cleared by hardware.

0: No action

1: Re-initializes the counter and generates an update of the registers. The prescaler counter is also cleared and the prescaler ratio is not affected. The counter is cleared.



### 14.4.6 TIM9 capture/compare mode register 1 (TIMx\_CCMR1)

Address offset: 0x18

Reset value: 0x0000

The channels can be used in input (capture mode) or in output (compare mode). The direction of a channel is defined by configuring the corresponding CCxS bits. All the other bits in this register have different functions in input and output modes. For a given bit, OCxx describes its function when the channel is configured in output mode, ICxx describes its function when the channel is configured in input mode. So you must take care that the same bit can have different meanings for the input stage and the output stage.

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Res.	OC2M[2:0]			OC2PE	OC2FE	CC2S[1:0]		Res.	OC1M[2:0]			OC1PE	OC1FE	CC1S[1:0]	
IC2F[3:0]				IC2PSC[1:0]				IC1F[3:0]				IC1PSC[1:0]			
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

#### Output compare mode

Bits 14:12 **OC2M[2:0]**: Output compare 2 mode

Bit 11 **OC2PE**: Output compare 2 preload enable

Bit 10 **OC2FE**: Output compare 2 fast enable

Bits 9:8 **CC2S[1:0]**: Capture/Compare 2 selection

This bitfield defines the direction of the channel (input/output) as well as the used input.

00: CC2 channel is configured as output

01: CC2 channel is configured as input, IC2 is mapped on TI2

10: CC2 channel is configured as input, IC2 is mapped on TI1

11: CC2 channel is configured as input, IC2 is mapped on TRC. This mode works only if an internal trigger input is selected through the TS bit (TIMx\_SMCR register)

*Note: The CC2S bits are writable only when the channel is OFF (CC2E = 0 in TIMx\_CCER).*

Bits 6:4 **OC1M**: Output compare 1 mode

These bits define the behavior of the output reference signal OC1REF from which OC1 and OC1N are derived. OC1REF is active high whereas the active levels of OC1 and OC1N depend on the CC1P and CC1NP bits, respectively.

000: Frozen - The comparison between the output compare register TIMx\_CCR1 and the counter TIMx\_CNT has no effect on the outputs.(this mode is used to generate a timing base).

001: Set channel 1 to active level on match. The OC1REF signal is forced high when the TIMx\_CNT counter matches the capture/compare register 1 (TIMx\_CCR1).

010: Set channel 1 to inactive level on match. The OC1REF signal is forced low when the TIMx\_CNT counter matches the capture/compare register 1 (TIMx\_CCR1).

011: Toggle - OC1REF toggles when TIMx\_CNT=TIMx\_CCR1

100: Force inactive level - OC1REF is forced low

101: Force active level - OC1REF is forced high

110: PWM mode 1 - In upcounting, channel 1 is active as long as TIMx\_CNT<TIMx\_CCR1 else it is inactive. In downcounting, channel 1 is inactive (OC1REF=0) as long as TIMx\_CNT>TIMx\_CCR1, else it is active (OC1REF=1')

111: PWM mode 2 - In upcounting, channel 1 is inactive as long as TIMx\_CNT<TIMx\_CCR1 else it is active. In downcounting, channel 1 is active as long as TIMx\_CNT>TIMx\_CCR1 else it is inactive.

*Note: In PWM mode 1 or 2, the OCREF level changes only when the result of the comparison changes or when the output compare mode switches from "frozen" mode to "PWM" mode.*

**Bit 3 OC1PE:** Output compare 1 preload enable

0: Preload register on TIMx\_CCR1 disabled. TIMx\_CCR1 can be written at anytime, the new value is taken into account immediately

1: Preload register on TIMx\_CCR1 enabled. Read/Write operations access the preload register. TIMx\_CCR1 preload value is loaded into the active register at each update event

*Note: The PWM mode can be used without validating the preload register only in one-pulse mode (OPM bit set in the TIMx\_CR1 register). Else the behavior is not guaranteed.*

**Bit 2 OC1FE:** Output compare 1 fast enable

This bit is used to accelerate the effect of an event on the trigger in input on the CC output.  
0: CC1 behaves normally depending on the counter and CCR1 values even when the trigger is ON. The minimum delay to activate the CC1 output when an edge occurs on the trigger input is 5 clock cycles

1: An active edge on the trigger input acts like a compare match on the CC1 output. Then, OC is set to the compare level independently of the result of the comparison. Delay to sample the trigger input and to activate CC1 output is reduced to 3 clock cycles. OC1FE acts only if the channel is configured in PWM1 or PWM2 mode.

**Bits 1:0 CC1S:** Capture/Compare 1 selection

This bitfield defines the direction of the channel (input/output) as well as the used input.

00: CC1 channel is configured as output

01: CC1 channel is configured as input, IC1 is mapped on TI1

10: CC1 channel is configured as input, IC1 is mapped on TI2

11: CC1 channel is configured as input, IC1 is mapped on TRC. This mode works only if an internal trigger input is selected through the TS bit (TIMx\_SMCR register)

*Note: The CC1S bits are writable only when the channel is OFF (CC1E = 0 in TIMx\_CCER).*

## Input capture mode

Bits 15:12 **IC2F**: Input capture 2 filter

Bits 11:10 **IC2PSC[1:0]**: Input capture 2 prescaler

Bits 9:8 **CC2S**: Capture/compare 2 selection

This bitfield defines the direction of the channel (input/output) as well as the used input.

00: CC2 channel is configured as output

01: CC2 channel is configured as input, IC2 is mapped on TI2

10: CC2 channel is configured as input, IC2 is mapped on TI1

11: CC2 channel is configured as input, IC2 is mapped on TRC. This mode works only if an internal trigger input is selected through the TS bit (TIMx\_SMCR register)

*Note: The CC2S bits are writable only when the channel is OFF (CC2E = 0 in TIMx\_CCER).*

Bits 7:4 **IC1F**: Input capture 1 filter

This bitfield defines the frequency used to sample the TI1 input and the length of the digital filter applied to TI1. The digital filter is made of an event counter in which N events are needed to validate a transition on the output:

0000: No filter, sampling is done at  $f_{DTS}$  1000:  $f_{SAMPLING}=f_{DTS}/8$ , N=6

0001:  $f_{SAMPLING}=f_{CK\_INT}$ , N=2 1001:  $f_{SAMPLING}=f_{DTS}/8$ , N=8

0010:  $f_{SAMPLING}=f_{CK\_INT}$ , N=4 1010:  $f_{SAMPLING}=f_{DTS}/16$ , N=5

0011:  $f_{SAMPLING}=f_{CK\_INT}$ , N=8 1011:  $f_{SAMPLING}=f_{DTS}/16$ , N=6

0100:  $f_{SAMPLING}=f_{DTS}/2$ , N=6 1100:  $f_{SAMPLING}=f_{DTS}/16$ , N=8

0101:  $f_{SAMPLING}=f_{DTS}/2$ , N=8 1101:  $f_{SAMPLING}=f_{DTS}/32$ , N=5

0110:  $f_{SAMPLING}=f_{DTS}/4$ , N=6 1110:  $f_{SAMPLING}=f_{DTS}/32$ , N=6

0111:  $f_{SAMPLING}=f_{DTS}/4$ , N=8 1111:  $f_{SAMPLING}=f_{DTS}/32$ , N=8

Bits 3:2 **IC1PSC**: Input capture 1 prescaler

This bitfield defines the ratio of the prescaler acting on the CC1 input (IC1).

The prescaler is reset as soon as CC1E='0' (TIMx\_CCER register).

00: no prescaler, capture is done each time an edge is detected on the capture input

01: capture is done once every 2 events

10: capture is done once every 4 events

11: capture is done once every 8 events

Bits 1:0 **CC1S**: Capture/Compare 1 selection

This bitfield defines the direction of the channel (input/output) as well as the used input.

00: CC1 channel is configured as output

01: CC1 channel is configured as input, IC1 is mapped on TI1

10: CC1 channel is configured as input, IC1 is mapped on TI2

11: CC1 channel is configured as input, IC1 is mapped on TRC. This mode is working only if an internal trigger input is selected through TS bit (TIMx\_SMCR register)

*Note: The CC1S bits are writable only when the channel is OFF (CC1E = 0 in TIMx\_CCER).*

### 14.4.7 TIM9 capture/compare enable register (TIMx\_CCER)

Address offset: 0x20

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved								CC2NP	Res.	CC2P	CC2E	CC1NP	Res.	CC1P	CC1E
								rw		rw	rw	rw		rw	rw

Bits 15:8 Reserved, must be kept at reset value.

Bit 7 **CC2NP**: Capture/Compare 2 output Polarity  
refer to CC1NP description

Bits 6 Reserved, must be kept at reset value.

Bit 5 **CC2P**: Capture/Compare 2 output Polarity  
refer to CC1P description

Bit 4 **CC2E**: Capture/Compare 2 output enable  
refer to CC1E description

Bit 3 **CC1NP**: Capture/Compare 1 complementary output Polarity  
CC1 channel configured as output: CC1NP must be kept cleared  
CC1 channel configured as input: CC1NP is used in conjunction with CC1P to define  
TI1FP1/TI2FP1 polarity (refer to CC1P description).

Bit 2 Reserved, must be kept at reset value.

Bit 1 **CC1P**: Capture/Compare 1 output Polarity.

**CC1 channel configured as output:**

0: OC1 active high.

1: OC1 active low.

**CC1 channel configured as input:**

CC1NP/CC1P bits select TI1FP1 and TI2FP1 polarity for trigger or capture operations.

00: noninverted/rising edge

Circuit is sensitive to TIxFP1 rising edge (capture, trigger in reset, external clock or trigger mode), TIxFP1 is not inverted (trigger in gated mode, encoder mode).

01: inverted/falling edge

Circuit is sensitive to TIxFP1 falling edge (capture, trigger in reset, external clock or trigger mode), TIxFP1 is inverted (trigger in gated mode, encoder mode).

10: reserved, do not use this configuration.

*Note:* 11: noninverted/both edges

*Circuit is sensitive to both TIxFP1 rising and falling edges (capture, trigger in reset, external clock or trigger mode), TIxFP1 is not inverted (trigger in gated mode). This configuration must not be used for encoder mode.*

Bit 0 **CC1E**: Capture/Compare 1 output enable.

**CC1 channel configured as output:**

0: Off - OC1 is not active.

1: On - OC1 signal is output on the corresponding output pin.

**CC1 channel configured as input:**

This bit determines if a capture of the counter value can actually be done into the input capture/compare register 1 (TIMx\_CCR1) or not.

0: Capture disabled.

1: Capture enabled.

**Table 58. Output control bit for standard OCx channels**

CCxE bit	OCx output state
0	Output disabled (OCx='0', OCx_EN='0')
1	OCx=OCxREF + Polarity, OCx_EN='1'

*Note:* The states of the external I/O pins connected to the standard OCx channels depend on the state of the OCx channel and on the GPIO registers.

**14.4.8 TIM9 counter (TIMx\_CNT)**

Address offset: 0x24

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
CNT[15:0]															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 15:0 **CNT[15:0]**: Counter value

**14.4.9 TIM9 prescaler (TIMx\_PSC)**

Address offset: 0x28

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
PSC[15:0]															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 15:0 **PSC[15:0]**: Prescaler value

The counter clock frequency CK\_CNT is equal to  $f_{CK\_PSC} / (PSC[15:0] + 1)$ .

PSC contains the value to be loaded into the active prescaler register at each update event.

**14.4.10 TIM9 auto-reload register (TIMx\_ARR)**

Address offset: 0x2C

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
ARR[15:0]															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 15:0 **ARR[15:0]**: Auto-reload value

ARR is the value to be loaded into the actual auto-reload register.

Refer to the [Section 14.3.1: Time-base unit on page 373](#) for more details about ARR update and behavior.

The counter is blocked while the auto-reload value is null.

### 14.4.11 TIM9 capture/compare register 1 (TIMx\_CCR1)

Address offset: 0x34

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
CCR1[15:0]															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 15:0 **CCR1[15:0]**: Capture/Compare 1 value

**If channel CC1 is configured as output:**

CCR1 is the value to be loaded into the actual capture/compare 1 register (preload value). It is loaded permanently if the preload feature is not selected in the TIMx\_CCMR1 register (OC1PE bit). Else the preload value is copied into the active capture/compare 1 register when an update event occurs.

The active capture/compare register contains the value to be compared to the TIMx\_CNT counter and signaled on the OC1 output.

**If channel CC1 is configured as input:**

CCR1 is the counter value transferred by the last input capture 1 event (IC1).

### 14.4.12 TIM9 capture/compare register 2 (TIMx\_CCR2)

Address offset: 0x38

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
CCR2[15:0]															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 15:0 **CCR2[15:0]**: Capture/Compare 2 value

**If channel CC2 is configured as output:**

CCR2 is the value to be loaded into the actual capture/compare 2 register (preload value). It is loaded permanently if the preload feature is not selected in the TIMx\_CCMR2 register (OC2PE bit). Else the preload value is copied into the active capture/compare 2 register when an update event occurs.

The active capture/compare register contains the value to be compared to the TIMx\_CNT counter and signalled on the OC2 output.

**If channel CC2 is configured as input:**

CCR2 is the counter value transferred by the last input capture 2 event (IC2).

### 14.4.13 TIM9 register map

TIM9 registers are mapped as 16-bit addressable registers as described below:

**Table 59. TIM9 register map and reset values**

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0																							
0x00	<b>TIMx_CR1</b> Reset value	Reserved																							CKD [1:0]	ARPE	Reserved			OPM	URS	UDIS	CEN	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0			
0x08	<b>TIMx_SMCR</b> Reset value	Reserved																							MSM	TS[2:0]			Reserved	SMS[2:0]			0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0			
0x0C	<b>TIMx_DIER</b> Reset value	Reserved																							TIE	Reserved			CC2IE	CC1IE	UIE	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	
0x10	<b>TIMx_SR</b> Reset value	Reserved																							CC2OF	CC1OF	Reserved			TIF	Reserved			CC2IF	CC1IF	UIF	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0		
0x14	<b>TIMx_EGR</b> Reset value	Reserved																							TG	Reserved			CC2G	CC1G	UG	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x18	<b>TIMx_CCMR1</b> Output Compare mode Reset value	Reserved													OC2M [2:0]	OC2PE	OC2FE	CC2S [1:0]	Reserved	OC1M [2:0]	OC1PE	OC1FE	CC1S [1:0]	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0															
	<b>TIMx_CCMR1</b> Input Capture mode Reset value	Reserved													IC2F[3:0]	IC2PSC [1:0]	CC2S [1:0]	IC1F[3:0]	IC1PSC [1:0]	CC1S [1:0]	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0																	
0x1C	Reserved																																																							
0x20	<b>TIMx_CCER</b> Reset value	Reserved																							CC2NP	Reserved	CC2P	CC2E	CC1NP	Reserved	CC1P	CC1E	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	
0x24	<b>TIMx_CNT</b> Reset value	Reserved													CNT[15:0]																0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0								
0x28	<b>TIMx_PSC</b> Reset value	Reserved													PSC[15:0]																0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0							
0x2C	<b>TIMx_ARR</b> Reset value	Reserved													ARR[15:0]																0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0							
0x30	Reserved																																																							
0x34	<b>TIMx_CCR1</b> Reset value	Reserved													CCR1[15:0]																0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0							



**Table 59. TIM9 register map and reset values (continued)**

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0				
0x38	TIMx_CCR2	Reserved																CCR2[15:0]																			
	Reset value																	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x3C to 0x4C	Reserved																																				

Refer to [Table 1 on page 38](#) for the register boundary addresses.



## 14.5 TIM10/11 registers

The peripheral registers have to be written by half-words (16 bits) or words (32 bits). Read accesses can be done by bytes (8 bits), half-words (16 bits) or words (32 bits).

### 14.5.1 TIM10/11 control register 1 (TIMx\_CR1)

Address offset: 0x00

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0		
Reserved						CKD[1:0]			ARPE			Reserved			URS	UDIS	CEN
						rw	rw	rw				rw	rw	rw			

Bits 15:10 Reserved, must be kept at reset value.

Bits 9:8 **CKD**: Clock division

This bit-field indicates the division ratio between the timer clock (CK\_INT) frequency and sampling clock used by the digital filters (TIx),

00:  $t_{DTS} = t_{CK\_INT}$

01:  $t_{DTS} = 2 \times t_{CK\_INT}$

10:  $t_{DTS} = 4 \times t_{CK\_INT}$

11: Reserved

Bit 7 **ARPE**: Auto-reload preload enable

0: TIMx\_ARR register is not buffered

1: TIMx\_ARR register is buffered

Bits 6:3 Reserved, must be kept at reset value.

Bit 2 **URS**: Update request source

This bit is set and cleared by software to select the update interrupt (UEV) sources.

0: Any of the following events generate an UEV if enabled:

- Counter overflow
- Setting the UG bit

1: Only counter overflow generates an UEV if enabled.

Bit 1 **UDIS**: Update disable

This bit is set and cleared by software to enable/disable update interrupt (UEV) event generation.

0: UEV enabled. An UEV is generated by one of the following events:

- Counter overflow
- Setting the UG bit.

Buffered registers are then loaded with their preload values.

1: UEV disabled. No UEV is generated, shadow registers keep their value (ARR, PSC, CCRx). The counter and the prescaler are reinitialized if the UG bit is set.

Bit 0 **CEN**: Counter enable

0: Counter disabled

1: Counter enabled

### 14.5.2 TIM10/11 Interrupt enable register (TIMx\_DIER)

Address offset: 0x0C

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved														CC1IE	UIE
														rw	rw

Bits 15:2 Reserved, must be kept at reset value.

Bit 1 **CC1IE**: Capture/Compare 1 interrupt enable

0: CC1 interrupt disabled

1: CC1 interrupt enabled

Bit 0 **UIE**: Update interrupt enable

0: Update interrupt disabled

1: Update interrupt enabled

### 14.5.3 TIM status register (TIMx\_SR)

Address offset: 0x10

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved						CC1OF	Reserved							CC1IF	UIF
						rc_w0								rc_w0	rc_w0

Bits 15:10 Reserved, must be kept at reset value.

Bit 9 **CC1OF**: Capture/Compare 1 overcapture flag

This flag is set by hardware only when the corresponding channel is configured in input capture mode. It is cleared by software by writing it to '0'.

0: No overcapture has been detected.

1: The counter value has been captured in TIMx\_CCR1 register while CC1IF flag was already set

Bits 8:2 Reserved, must be kept at reset value.

Bit 1 **CC1IF**: Capture/compare 1 interrupt flag

**If channel CC1 is configured as output:**

This flag is set by hardware when the counter matches the compare value. It is cleared by software.

0: No match.

1: The content of the counter TIMx\_CNT matches the content of the TIMx\_CCR1 register.

When the contents of TIMx\_CCR1 are greater than the contents of TIMx\_ARR, the CC1IF bit goes high on the counter overflow.

**If channel CC1 is configured as input:**

This bit is set by hardware on a capture. It is cleared by software or by reading the TIMx\_CCR1 register.

0: No input capture occurred.

1: The counter value has been captured in TIMx\_CCR1 register (an edge has been detected on IC1 which matches the selected polarity).

Bit 0 **UIF**: Update interrupt flag

This bit is set by hardware on an update event. It is cleared by software.

0: No update occurred.

1: Update interrupt pending. This bit is set by hardware when the registers are updated:

- At overflow and if UDIS='0' in the TIMx\_CR1 register.
- When CNT is reinitialized by software using the UG bit in TIMx\_EGR register, if URS='0' and UDIS='0' in the TIMx\_CR1 register.

### 14.5.4 TIM event generation register (TIMx\_EGR)

Address offset: 0x14

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved														CC1G	UG
														w	w

Bits 15:2 Reserved, must be kept at reset value.

Bit 1 **CC1G**: Capture/compare 1 generation

This bit is set by software in order to generate an event, it is automatically cleared by hardware.

0: No action

1: A capture/compare event is generated on channel 1:

**If channel CC1 is configured as output:**

CC1IF flag is set, Corresponding interrupt or is sent if enabled.

**If channel CC1 is configured as input:**

The current value of the counter is captured in TIMx\_CCR1 register. The CC1IF flag is set, the corresponding interrupt is sent if enabled. The CC1OF flag is set if the CC1IF flag was already high.

Bit 0 **UG**: Update generation

This bit can be set by software, it is automatically cleared by hardware.

0: No action

1: Re-initialize the counter and generates an update of the registers. Note that the prescaler counter is cleared too (anyway the prescaler ratio is not affected). The counter is cleared.

### 14.5.5 TIM10/11 capture/compare mode register 1 (TIMx\_CCMR1)

Address offset: 0x18

Reset value: 0x0000

The channels can be used in input (capture mode) or in output (compare mode). The direction of a channel is defined by configuring the corresponding CCxS bits. All the other bits of this register have a different function in input and in output mode. For a given bit, OCxx describes its function when the channel is configured in output, ICxx describes its function when the channel is configured in input. So you must take care that the same bit can have a different meaning for the input stage and for the output stage.

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved								OC1M[2:0]			OC1PE	OC1FE	CC1S[1:0]		
Reserved								IC1F[3:0]				IC1PSC[1:0]		CC1S[1:0]	
								rw	rw	rw	rw	rw	rw	rw	rw

## Output compare mode

Bits 15:7 Reserved, must be kept at reset value.

Bits 6:4 **OC1M**: Output compare 1 mode

These bits define the behavior of the output reference signal OC1REF from which OC1 is derived. OC1REF is active high whereas OC1 active level depends on CC1P bit.

000: Frozen. The comparison between the output compare register TIMx\_CCR1 and the counter TIMx\_CNT has no effect on the outputs.

001: Set channel 1 to active level on match. OC1REF signal is forced high when the counter TIMx\_CNT matches the capture/compare register 1 (TIMx\_CCR1).

010: Set channel 1 to inactive level on match. OC1REF signal is forced low when the counter TIMx\_CNT matches the capture/compare register 1 (TIMx\_CCR1).

011: Toggle - OC1REF toggles when TIMx\_CNT = TIMx\_CCR1.

100: Force inactive level - OC1REF is forced low.

101: Force active level - OC1REF is forced high.

110: PWM mode 1 - Channel 1 is active as long as TIMx\_CNT < TIMx\_CCR1 else inactive.

111: PWM mode 2 - Channel 1 is inactive as long as TIMx\_CNT < TIMx\_CCR1 else active.

*Note: In PWM mode 1 or 2, the OCREF level changes when the result of the comparison changes or when the output compare mode switches from frozen to PWM mode.*

Bit 3 **OC1PE**: Output compare 1 preload enable

0: Preload register on TIMx\_CCR1 disabled. TIMx\_CCR1 can be written at anytime, the new value is taken in account immediately.

1: Preload register on TIMx\_CCR1 enabled. Read/Write operations access the preload register. TIMx\_CCR1 preload value is loaded in the active register at each update event.

*Note: The PWM mode can be used without validating the preload register only in one pulse mode (OPM bit set in TIMx\_CR1 register). Else the behavior is not guaranteed.*

Bit 2 **OC1FE**: Output compare 1 fast enable

This bit is used to accelerate the effect of an event on the trigger in input on the CC output.  
0: CC1 behaves normally depending on counter and CCR1 values even when the trigger is ON. The minimum delay to activate CC1 output when an edge occurs on the trigger input is 5 clock cycles.

1: An active edge on the trigger input acts like a compare match on CC1 output. OC is then set to the compare level independently of the result of the comparison. Delay to sample the trigger input and to activate CC1 output is reduced to 3 clock cycles. OC1FE acts only if the channel is configured in PWM1 or PWM2 mode.

Bits 1:0 **CC1S**: Capture/Compare 1 selection

This bit-field defines the direction of the channel (input/output) as well as the used input.  
00: CC1 channel is configured as output.

01: CC1 channel is configured as input, IC1 is mapped on TI1.

10:

11:

*Note: CC1S bits are writable only when the channel is OFF (CC1E = 0 in TIMx\_CCER).*

## Input capture mode

Bits 15:8 Reserved, must be kept at reset value.

Bits 7:4 **IC1F**: Input capture 1 filter

This bit-field defines the frequency used to sample TI1 input and the length of the digital filter applied to TI1. The digital filter is made of an event counter in which N events are needed to validate a transition on the output:

0000: No filter, sampling is done at  $f_{DTS}$   
 1000:  $f_{SAMPLING}=f_{DTS}/8$ , N=6  
 0001:  $f_{SAMPLING}=f_{CK\_INT}$ , N=2  
 1001:  $f_{SAMPLING}=f_{DTS}/8$ , N=8  
 0010:  $f_{SAMPLING}=f_{CK\_INT}$ , N=4  
 1010:  $f_{SAMPLING}=f_{DTS}/16$ , N=5  
 0011:  $f_{SAMPLING}=f_{CK\_INT}$ , N=8  
 1011:  $f_{SAMPLING}=f_{DTS}/16$ , N=6  
 0100:  $f_{SAMPLING}=f_{DTS}/2$ , N=6  
 1100:  $f_{SAMPLING}=f_{DTS}/16$ , N=8  
 0101:  $f_{SAMPLING}=f_{DTS}/2$ , N=8  
 1101:  $f_{SAMPLING}=f_{DTS}/32$ , N=5  
 0110:  $f_{SAMPLING}=f_{DTS}/4$ , N=6  
 1110:  $f_{SAMPLING}=f_{DTS}/32$ , N=6  
 0111:  $f_{SAMPLING}=f_{DTS}/4$ , N=8  
 1111:  $f_{SAMPLING}=f_{DTS}/32$ , N=8

Bits 3:2 **IC1PSC**: Input capture 1 prescaler

This bit-field defines the ratio of the prescaler acting on CC1 input (IC1).

The prescaler is reset as soon as CC1E='0' (TIMx\_CCER register).

00: no prescaler, capture is done each time an edge is detected on the capture input  
 01: capture is done once every 2 events  
 10: capture is done once every 4 events  
 11: capture is done once every 8 events

Bits 1:0 **CC1S**: Capture/Compare 1 selection

This bit-field defines the direction of the channel (input/output) as well as the used input.

00: CC1 channel is configured as output  
 01: CC1 channel is configured as input, IC1 is mapped on TI1  
 10: Reserved  
 11: Reserved

*Note: CC1S bits are writable only when the channel is OFF (CC1E = 0 in TIMx\_CCER).*

### 14.5.6 TIM10/11 capture/compare enable register (TIMx\_CCER)

Address offset: 0x20

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved												CC1NP	Res.	CC1P	CC1E
												rw		rw	rw

Bits 15:4 Reserved, must be kept at reset value.

Bit 3 **CC1NP**: Capture/Compare 1 complementary output Polarity.

CC1 channel configured as output: CC1NP must be kept cleared.

CC1 channel configured as input: CC1NP bit is used in conjunction with CC1P to define TI1FP1 polarity (refer to CC1P description).

Bit 2 Reserved, must be kept at reset value.

Bit 1 **CC1P**: Capture/Compare 1 output Polarity.

**CC1 channel configured as output:**

0: OC1 active high

1: OC1 active low

**CC1 channel configured as input:**

The CC1P bit selects TI1FP1 and TI2FP1 polarity for trigger or capture operations.

00: noninverted/rising edge

Circuit is sensitive to TI1FP1 rising edge (capture mode), TI1FP1 is not inverted.

01: inverted/falling edge

Circuit is sensitive to TI1FP1 falling edge (capture mode), TI1FP1 is inverted.

10: reserved, do not use this configuration.

11: noninverted/both edges

Circuit is sensitive to both TI1FP1 rising and falling edges (capture mode), TI1FP1 is not inverted.

Bit 0 **CC1E**: Capture/Compare 1 output enable.

**CC1 channel configured as output:**

0: Off - OC1 is not active

1: On - OC1 signal is output on the corresponding output pin

**CC1 channel configured as input:**

This bit determines if a capture of the counter value can actually be done into the input capture/compare register 1 (TIMx\_CCR1) or not.

0: Capture disabled

1: Capture enabled

**Table 60. Output control bit for standard OCx channels**

CCxE bit	OCx output state
0	Output Disabled (OCx='0', OCx_EN='0')
1	OCx=OCxREF + Polarity, OCx_EN='1'

*Note:* The state of the external I/O pins connected to the standard OCx channels depends on the OCx channel state and the GPIO registers.

### 14.5.7 TIM10/11 counter (TIMx\_CNT)

Address offset: 0x24

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
CNT[15:0]															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 15:0 **CNT[15:0]**: Counter value

### 14.5.8 TIM10/11 prescaler (TIMx\_PSC)

Address offset: 0x28

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
PSC[15:0]															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 15:0 **PSC[15:0]**: Prescaler value

The counter clock frequency CK\_CNT is equal to  $f_{CK\_PSC} / (PSC[15:0] + 1)$ .

PSC contains the value to be loaded in the active prescaler register at each update event.

### 14.5.9 TIM10/11 auto-reload register (TIMx\_ARR)

Address offset: 0x2C

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
ARR[15:0]															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 15:0 **ARR[15:0]**: Auto-reload value

ARR is the value to be loaded in the actual auto-reload register.

Refer to [Section 14.3.1: Time-base unit on page 373](#) for more details about ARR update and behavior.

The counter is blocked while the auto-reload value is null.



### 14.5.10 TIM10/11 capture/compare register 1 (TIMx\_CCR1)

Address offset: 0x34

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
CCR1[15:0]															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 15:0 **CCR1[15:0]**: Capture/Compare 1 value

**If channel CC1 is configured as output:**

CCR1 is the value to be loaded in the actual capture/compare 1 register (preload value).

It is loaded permanently if the preload feature is not selected in the TIMx\_CCMR1 register (bit OC1PE). Else the preload value is copied in the active capture/compare 1 register when an update event occurs.

The active capture/compare register contains the value to be compared to the counter TIMx\_CNT and signaled on OC1 output.

**If channel CC1 is configured as input:**

CCR1 is the counter value transferred by the last input capture 1 event (IC1).

### 14.5.11 TIM11 option register 1 (TIM11\_OR)

Address offset: 0x50

Reset value: 0x0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved														TI1_RMP[1:0]	
														rw	

Bits 15:2 Reserved, must be kept at reset value.

Bits 1:0 **TI1\_RMP[1:0]**: TIM11 Input 1 remapping capability

Set and cleared by software.

00,01,11: TIM11 Channel1 is connected to the GPIO (refer to the Alternate function mapping table in the datasheets).

10: HSE\_RTC clock (HSE divided by programmable prescaler) is connected to the TIM11\_CH1 input for measurement purposes.



Table 61. TIM10/11 register map and reset values (continued)

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0x50	TIMx_OR	Reserved																									TIM_RMP						
	Reset value																												0	0			

Refer to [Table 1 on page 38](#) for the register boundary addresses.

## 15 Independent watchdog (IWDG)

### 15.1 IWDG introduction

The devices have two embedded watchdog peripherals which offer a combination of high safety level, timing accuracy and flexibility of use. Both watchdog peripherals (Independent and Window) serve to detect and resolve malfunctions due to software failure, and to trigger system reset or an interrupt (window watchdog only) when the counter reaches a given timeout value.

The independent watchdog (IWDG) is clocked by its own dedicated low-speed clock (LSI) and thus stays active even if the main clock fails. The window watchdog (WWDG) clock is prescaled from the APB1 clock and has a configurable time-window that can be programmed to detect abnormally late or early application behavior.

The IWDG is best suited to applications which require the watchdog to run as a totally independent process outside the main application, but have lower timing accuracy constraints. The WWDG is best suited to applications which require the watchdog to react within an accurate timing window. For further information on the window watchdog, refer to [Section 16 on page 420](#).

### 15.2 IWDG main features

- Free-running downcounter
- clocked from an independent RC oscillator (can operate in Standby and Stop modes)
- Reset (if watchdog activated) when the downcounter value of 0x000 is reached

### 15.3 IWDG functional description

[Figure 156](#) shows the functional blocks of the independent watchdog module.

When the independent watchdog is started by writing the value 0xCCCC in the Key register (IWDG\_KR), the counter starts counting down from the reset value of 0xFFFF. When it reaches the end of count value (0x000) a reset signal is generated (IWDG reset).

Whenever the key value 0xAAAA is written in the IWDG\_KR register, the IWDG\_RLR value is reloaded in the counter and the watchdog reset is prevented.

#### 15.3.1 Hardware watchdog

If the “Hardware watchdog” feature is enabled through the device option bits, the watchdog is automatically enabled at power-on, and will generate a reset unless the Key register is written by the software before the counter reaches end of count.

#### 15.3.2 Register access protection

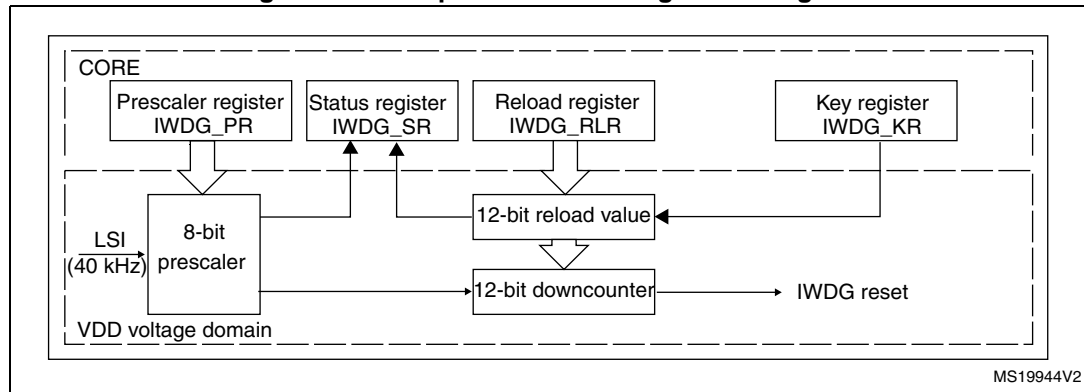
Write access to the IWDG\_PR and IWDG\_RLR registers is protected. To modify them, you must first write the code 0x5555 in the IWDG\_KR register. A write access to this register with a different value will break the sequence and register access will be protected again. This implies that it is the case of the reload operation (writing 0xAAAA).

A status register is available to indicate that an update of the prescaler or the down-counter reload value is on going.

### 15.3.3 Debug mode

When the microcontroller enters debug mode (Cortex<sup>®</sup>-M4 with FPU core halted), the IWDG counter either continues to work normally or stops, depending on DBG\_IWDG\_STOP configuration bit in DBG module. For more details, refer to [Section 23.16.2: Debug support for timers, watchdog and I2C](#).

Figure 156. Independent watchdog block diagram



Note: The watchdog function is implemented in the  $V_{DD}$  voltage domain that is still functional in Stop and Standby modes.

Table 62. Min/max IWDG timeout period at 32 kHz (LSI)<sup>(1)</sup>

Prescaler divider	PR[2:0] bits	Min timeout (ms) RL[11:0]= 0x000	Max timeout (ms) RL[11:0]= 0xFFFF
/4	0	0.125	512
/8	1	0.25	1024
/16	2	0.5	2048
/32	3	1	4096
/64	4	2	8192
/128	5	4	16384
/256	6		32768

1. These timings are given for a 32 kHz clock but the microcontroller internal RC frequency can vary. Please refer to the LSI oscillator characteristics table in the device datasheet for maximum and minimum values.



### 15.4.3 Reload register (IWDG\_RLR)

Address offset: 0x08

Reset value: 0x0000 0FFF (reset by Standby mode)

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0																	
Reserved																		RL[11:0]																														
																		rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 31:12 Reserved, must be kept at reset value.

Bits11:0 **RL[11:0]**: Watchdog counter reload value

These bits are write access protected see [Section 15.3.2](#). They are written by software to define the value to be loaded in the watchdog counter each time the value AAAAh is written in the IWDG\_KR register. The watchdog counter counts down from this value. The timeout period is a function of this value and the clock prescaler. Refer to [Table 62](#).

The RVU bit in the IWDG\_SR register must be reset in order to be able to change the reload value.

*Note: Reading this register returns the reload value from the VDD voltage domain. This value may not be up to date/valid if a write operation to this register is ongoing on this register. For this reason the value read from this register is valid only when the RVU bit in the IWDG\_SR register is reset.*

### 15.4.4 Status register (IWDG\_SR)

Address offset: 0x0C

Reset value: 0x0000 0000 (not reset by Standby mode)

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved																RVU		PVU													
																r	r	r	r												

Bits 31:2 Reserved, must be kept at reset value.

Bit 1 **RVU**: Watchdog counter reload value update

This bit is set by hardware to indicate that an update of the reload value is ongoing. It is reset by hardware when the reload value update operation is completed in the V<sub>DD</sub> voltage domain (takes up to 5 RC 40 kHz cycles).

Reload value can be updated only when RVU bit is reset.

Bit 0 **PVU**: Watchdog prescaler value update

This bit is set by hardware to indicate that an update of the prescaler value is ongoing. It is reset by hardware when the prescaler update operation is completed in the V<sub>DD</sub> voltage domain (takes up to 5 RC 40 kHz cycles).

Prescaler value can be updated only when PVU bit is reset.

*Note: If several reload values or prescaler values are used by application, it is mandatory to wait until RVU bit is reset before changing the reload value and to wait until PVU bit is reset before changing the prescaler value. However, after updating the prescaler and/or the reload value it is not necessary to wait until RVU or PVU is reset before continuing code execution (even in case of low-power mode entry, the write operation is taken into account and will complete)*

### 15.4.5 IWDG register map

The following table gives the IWDG register map and reset values.

**Table 63. IWDG register map and reset values**

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0																	
0x00	IWDG_KR	Reserved															KEY[15:0]																																	
	Reset value																0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0			
0x04	IWDG_PR	Reserved																								PR[2:0]																								
	Reset value																									0	0	0																						
0x08	IWDG_RLR	Reserved																			RL[11:0]																													
	Reset value																				1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
0x0C	IWDG_SR	Reserved																								RVU	PVU																							
	Reset value																									0	0																							

Refer to [Table 1 on page 38](#) for the register boundary addresses.



## 16 Window watchdog (WWDG)

### 16.1 WWDG introduction

The window watchdog is used to detect the occurrence of a software fault, usually generated by external interference or by unforeseen logical conditions, which causes the application program to abandon its normal sequence. The watchdog circuit generates an MCU reset on expiry of a programmed time period, unless the program refreshes the contents of the downcounter before the T6 bit becomes cleared. An MCU reset is also generated if the 7-bit downcounter value (in the control register) is refreshed before the downcounter has reached the window register value. This implies that the counter must be refreshed in a limited window.

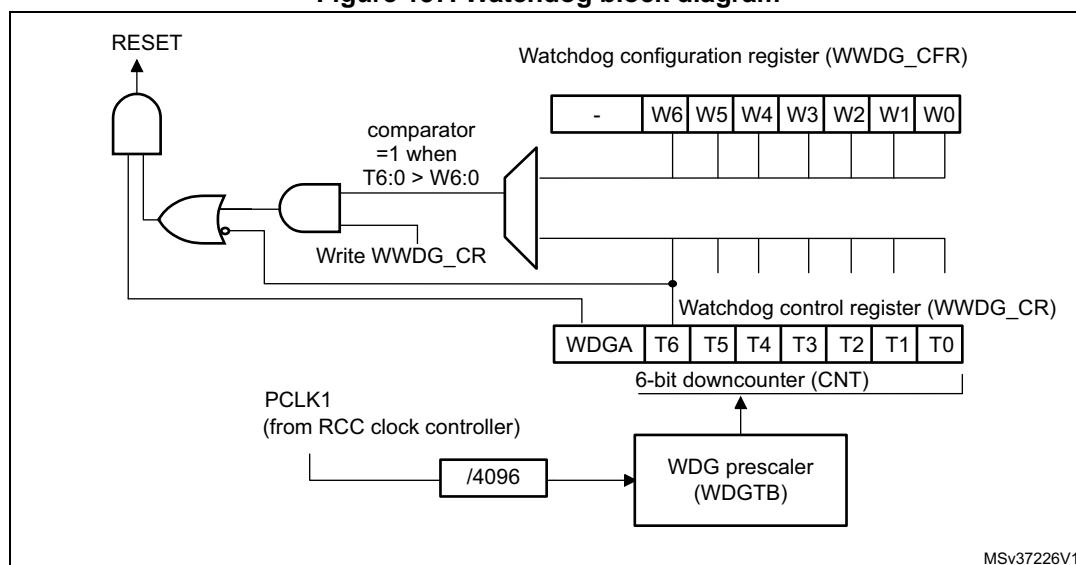
### 16.2 WWDG main features

- Programmable free-running downcounter
- Conditional reset
  - Reset (if watchdog activated) when the downcounter value becomes less than 0x40
  - Reset (if watchdog activated) if the downcounter is reloaded outside the window (see [Figure 158](#))
- Early wakeup interrupt (EWI): triggered (if enabled and the watchdog activated) when the downcounter is equal to 0x40.

### 16.3 WWDG functional description

If the watchdog is activated (the WDGA bit is set in the WWDG\_CR register) and when the 7-bit downcounter (T[6:0] bits) rolls over from 0x40 to 0x3F (T6 becomes cleared), it initiates a reset. If the software reloads the counter while the counter is greater than the value stored in the window register, then a reset is generated.

Figure 157. Watchdog block diagram



The application program must write in the WWDG\_CR register at regular intervals during normal operation to prevent an MCU reset. This operation must occur only when the counter value is lower than the window register value. The value to be stored in the WWDG\_CR register must be between 0xFF and 0xC0.

### Enabling the watchdog

The watchdog is always disabled after a reset. It is enabled by setting the WDGA bit in the WWDG\_CR register, then it cannot be disabled again except by a reset.

### Controlling the downcounter

This downcounter is free-running, counting down even if the watchdog is disabled. When the watchdog is enabled, the T6 bit must be set to prevent generating an immediate reset.

The T[5:0] bits contain the number of increments which represents the time delay before the watchdog produces a reset. The timing varies between a minimum and a maximum value due to the unknown status of the prescaler when writing to the WWDG\_CR register (see [Figure 158](#)). The Configuration register (WWDG\_CFR) contains the high limit of the window: To prevent a reset, the downcounter must be reloaded when its value is lower than the window register value and greater than 0x3F. [Figure 158](#) describes the window watchdog process.

*Note: The T6 bit can be used to generate a software reset (the WDGA bit is set and the T6 bit is cleared).*

### Advanced watchdog interrupt feature

The Early Wakeup Interrupt (EWI) can be used if specific safety operations or data logging must be performed before the actual reset is generated. The EWI interrupt is enabled by setting the EWI bit in the WWDG\_CFR register. When the downcounter reaches the value 0x40, an EWI interrupt is generated and the corresponding interrupt service routine (ISR) can be used to trigger specific actions (such as communications or data logging), before resetting the device.

In some applications, the EWI interrupt can be used to manage a software system check and/or system recovery/graceful degradation, without generating a WWDG reset. In this case, the corresponding interrupt service routine (ISR) should reload the WWDG counter to avoid the WWDG reset, then trigger the required actions.

The EWI interrupt is cleared by writing '0' to the EWIF bit in the WWDG\_SR register.

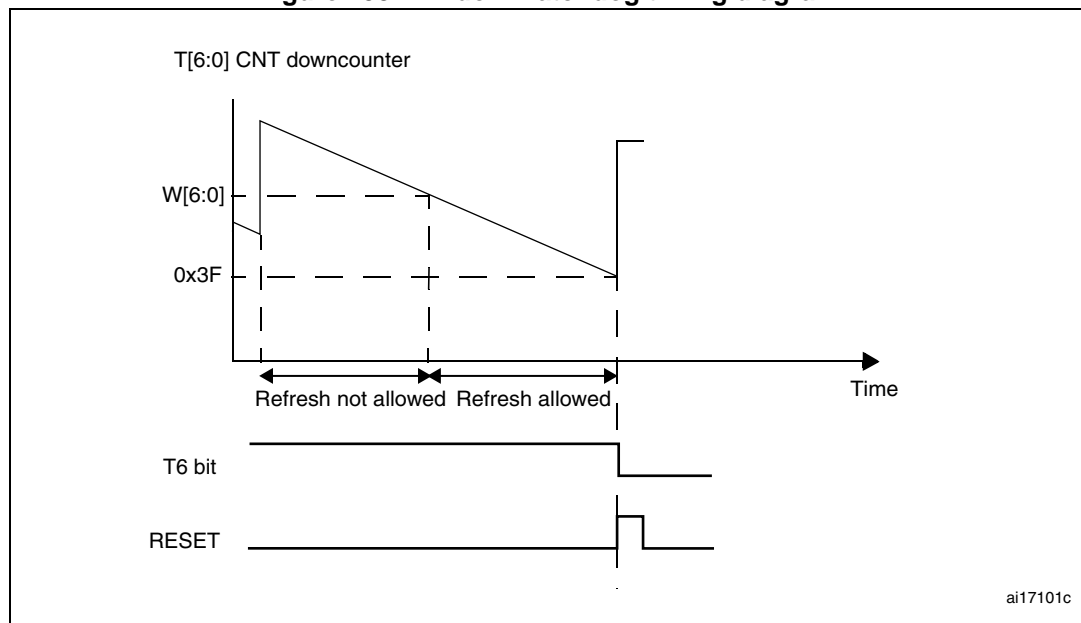
*Note:* When the EWI interrupt cannot be served, e.g. due to a system lock in a higher priority task, the WWDG reset will eventually be generated.

## 16.4 How to program the watchdog timeout

You can use the formula in [Figure 158](#) to calculate the WWDG timeout.

**Warning:** When writing to the WWDG\_CR register, always write 1 in the T6 bit to avoid generating an immediate reset.

Figure 158. Window watchdog timing diagram



The formula to calculate the timeout value is given by:

$$t_{WWDG} = t_{PCLK1} \times 4096 \times 2^{WDGTB[1:0]} \times (T[5:0] + 1) \quad (\text{ms})$$

where:

- $t_{WWDG}$ : WWDG timeout
- $t_{PCLK1}$ : APB1 clock period measured in ms
- 4096: value corresponding to internal divider

As an example, let us assume APB1 frequency is equal to 24 MHz, WDGTB[1:0] is set to 3 and T[5:0] is set to 63:

$$t_{\text{WWDG}} = 1/24000 \times 4096 \times 2^3 \times (63 + 1) = 21,85\text{ms}$$

Refer to the table below for the minimum and maximum values of the  $t_{\text{WWDG}}$ .

**Table 64. Minimum and maximum timeout values at 30 MHz ( $f_{\text{PCLK1}}$ )**

Prescaler	WDGTB	Min timeout ( $\mu\text{s}$ ) T[5:0] = 0x00	Max timeout (ms) T[5:0] = 0x3F
1	0	136.53	8.74
2	1	273.07	17.48
4	2	546.13	34.95
8	3	1092.27	69.91

## 16.5 Debug mode

When the microcontroller enters debug mode (Cortex<sup>®</sup>-M4 with FPU core halted), the WWDG counter either continues to work normally or stops, depending on DBG\_WWDG\_STOP configuration bit in DBG module. For more details, refer to [Section 23.16.2: Debug support for timers, watchdog and I2C](#).

## 16.6 WWDG registers

Refer to [Section 1.1 on page 34](#) for a list of abbreviations used in register descriptions.  
 The peripheral registers have to be accessed by half-words (16 bits) or words (32 bits).

### 16.6.1 Control register (WWDG\_CR)

Address offset: 0x00

Reset value: 0x0000 007F

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved															
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved								WDGA	T[6:0]						
								rs	rw						

Bits 31:8 Reserved, must be kept at reset value.

Bit 7 **WDGA**: Activation bit

This bit is set by software and only cleared by hardware after a reset. When WDGA = 1, the watchdog can generate a reset.

- 0: Watchdog disabled
- 1: Watchdog enabled

Bits 6:0 **T[6:0]**: 7-bit counter (MSB to LSB)

These bits contain the value of the watchdog counter. It is decremented every  $(4096 \times 2^{WDGTB[1:0]})$  PCLK1 cycles. A reset is produced when it rolls over from 0x40 to 0x3F (T6 becomes cleared).

### 16.6.2 Configuration register (WWDG\_CFR)

Address offset: 0x04

Reset value: 0x0000 007F

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved															
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved						EWI	WDGTB[1:0]		W[6:0]						
						rs	rw		rw						

Bit 31:10 Reserved, must be kept at reset value.

Bit 9 **EWI**: Early wakeup interrupt

When set, an interrupt occurs whenever the counter reaches the value 0x40. This interrupt is only cleared by hardware after a reset.

Bits 8:7 **WDGTB[1:0]**: Timer base

The time base of the prescaler can be modified as follows:

- 00: CK Counter Clock (PCLK1 div 4096) div 1
- 01: CK Counter Clock (PCLK1 div 4096) div 2
- 10: CK Counter Clock (PCLK1 div 4096) div 4
- 11: CK Counter Clock (PCLK1 div 4096) div 8

Bits 6:0 **W[6:0]**: 7-bit window value

These bits contain the window value to be compared to the downcounter.

### 16.6.3 Status register (WWDG\_SR)

Address offset: 0x08

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved															
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved														EWIF	
														rc_w0	

Bits 31:1 Reserved, must be kept at reset value.

Bit 0 **EWIF**: Early wakeup interrupt flag

This bit is set by hardware when the counter has reached the value 0x40. It must be cleared by software by writing '0'. A write of '1' has no effect. This bit is also set if the interrupt is not enabled.

### 16.6.4 WWDG register map

The following table gives the WWDG register map and reset values.

**Table 65. WWDG register map and reset values**

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
0x00	WWDG_CR	Reserved																							WDGA	T[6:0]								
	Reset value																								0	1	1	1	1	1	1	1		
0x04	WWDG_CFR	Reserved																							EWI	WDGTB1	WDGTB0	W[6:0]						
	Reset value																								0	0	0	1	1	1	1	1	1	1
0x08	WWDG_SR	Reserved																										EWIF						
	Reset value																											0						

Refer to [Table 1 on page 38](#) for the register boundary addresses.

## 17 Real-time clock (RTC)

### 17.1 Introduction

The real-time clock (RTC) is an independent BCD timer/counter. The RTC provides a time-of-day clock/calendar, two programmable alarm interrupts, and a periodic programmable wakeup flag with interrupt capability. The RTC also includes an automatic wakeup unit to manage low-power modes.

Two 32-bit registers contain the seconds, minutes, hours (12- or 24-hour format), day (day of week), date (day of month), month, and year, expressed in binary coded decimal format (BCD). The sub-seconds value is also available in binary format.

Compensations for 28-, 29- (leap year), 30-, and 31-day months are performed automatically. Daylight saving time compensation can also be performed.

Additional 32-bit registers contain the programmable alarm subseconds, seconds, minutes, hours, day, and date.

A digital calibration feature is available to compensate for any deviation in crystal oscillator accuracy.

After backup domain reset, all RTC registers are protected against possible parasitic write accesses.

As long as the supply voltage remains in the operating range, the RTC never stops, regardless of the device status (Run mode, low-power mode or under reset).



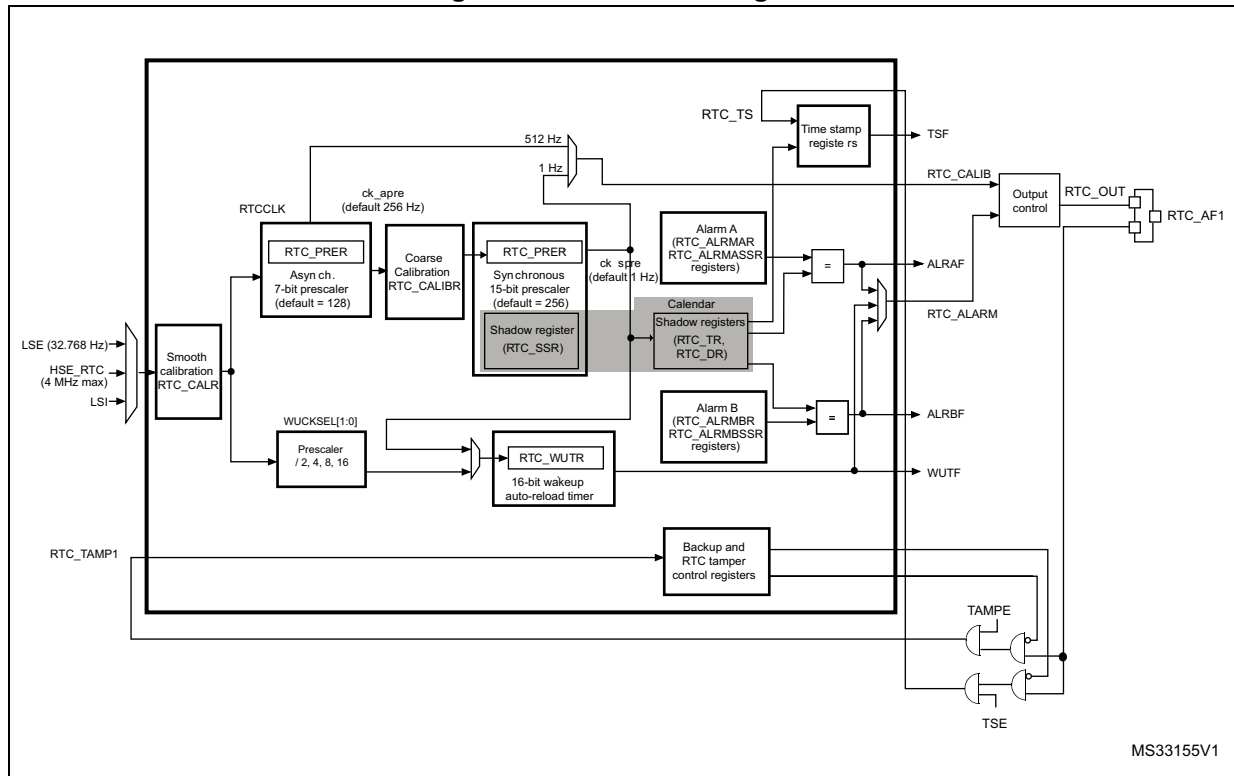
## 17.2 RTC main features

The RTC unit main features are the following (see [Figure 159: RTC block diagram](#)):

- Calendar with subseconds, seconds, minutes, hours (12 or 24 format), day (day of week), date (day of month), month, and year.
- Daylight saving compensation programmable by software.
- Two programmable alarms with interrupt function. The alarms can be triggered by any combination of the calendar fields.
- Automatic wakeup unit generating a periodic flag that triggers an automatic wakeup interrupt.
- Reference clock detection: a more precise second source clock (50 or 60 Hz) can be used to enhance the calendar precision.
- Accurate synchronization with an external clock using the subsecond shift feature.
- Maskable interrupts/events:
  - Alarm A
  - Alarm B
  - Wakeup interrupt
  - Timestamp
  - Tamper detection
- Digital calibration circuit (periodic counter correction)
  - 5 ppm accuracy
  - 0.95 ppm accuracy, obtained in a calibration window of several seconds
- Timestamp function for event saving (1 event)
- Tamper detection:
  - Tamper event with configurable filter and internal pull-up.
- 20 backup registers (80 bytes). The backup registers are reset when a tamper detection event occurs.
- Alternate function output (RTC\_OUT) which selects one of the following two outputs:
  - RTC\_CALIB: 512 Hz or 1 Hz clock output (with an LSE frequency of 32.768 kHz). This output is enabled by setting the COE bit in the RTC\_CR register. It is routed to the device RTC\_AF1 function.
  - RTC\_ALARM (Alarm A, Alarm B or wakeup). This output is selected by configuring the OSEL[1:0] bits in the RTC\_CR register. It is routed to the device RTC\_AF1 function.
- `_RTC` additional function inputs:
  - RTC\_TS: timestamp event detection. It is routed to the device RTC\_AF1 function.
  - RTC\_TAMP1: TAMPER1 event detection. It is routed to the device RTC\_AF1 function.
  - RTC\_REFIN: reference clock input (usually the mains, 50 or 60 Hz).

Refer to [Section 8.3.15: Selection of RTC functions](#) and the *STM32F401xx* datasheet pin definition table.

Figure 159. RTC block diagram



1. The RTC\_AF1 additional function is connected to PC13.

## 17.3 RTC functional description

### 17.3.1 Clock and prescalers

The RTC clock source (RTCCLK) is selected through the clock controller among the LSE clock, the LSI oscillator clock, and the HSE clock. For more information on the RTC clock source configuration, refer to [Section 6: Reset and clock control \(RCC\) for STM32F401xB/C and STM32F401xD/E](#).

A programmable prescaler stage generates a 1 Hz clock which is used to update the calendar. To minimize power consumption, the prescaler is split into 2 programmable prescalers (see [Figure 159: RTC block diagram](#)):

- A 7-bit asynchronous prescaler configured through the PREDIV\_A bits of the RTC\_PRER register.
- A 15-bit synchronous prescaler configured through the PREDIV\_S bits of the RTC\_PRER register.

*Note:* When both prescalers are used, it is recommended to configure the asynchronous prescaler to a high value to minimize consumption.

The asynchronous prescaler division factor is set to 128, and the synchronous division factor to 256, to obtain an internal clock frequency of 1 Hz (ck\_spre) with an LSE frequency of 32.768 kHz.

The minimum division factor is 1 and the maximum division factor is  $2^{22}$ .

This corresponds to a maximum input frequency of around 4 MHz.

$f_{\text{ck\_apre}}$  is given by the following formula:

$$f_{\text{CK\_APRE}} = \frac{f_{\text{RTCCLK}}}{\text{PREDIV\_A} + 1}$$

The  $\text{ck\_apre}$  clock is used to clock the binary  $\text{RTC\_SSR}$  subseconds downcounter. When it reaches 0,  $\text{RTC\_SSR}$  is reloaded with the content of  $\text{PREDIV\_S}$ .

$f_{\text{ck\_spre}}$  is given by the following formula:

$$f_{\text{CK\_SPRE}} = \frac{f_{\text{RTCCLK}}}{(\text{PREDIV\_S} + 1) \times (\text{PREDIV\_A} + 1)}$$

The  $\text{ck\_spre}$  clock can be used either to update the calendar or as timebase for the 16-bit wakeup auto-reload timer. To obtain short timeout periods, the 16-bit wakeup auto-reload timer can also run with the  $\text{RTCCLK}$  divided by the programmable 4-bit asynchronous prescaler (see [Section 17.3.4: Periodic auto-wakeup](#) for details).

### 17.3.2 Real-time clock and calendar

The RTC calendar time and date registers are accessed through shadow registers which are synchronized with  $\text{PCLK1}$  ( $\text{APB1}$  clock). They can also be accessed directly in order to avoid waiting for the synchronization duration.

- $\text{RTC\_SSR}$  for the subseconds
- $\text{RTC\_TR}$  for the time
- $\text{RTC\_DR}$  for the date

Every two  $\text{RTCCLK}$  periods, the current calendar value is copied into the shadow registers, and the  $\text{RSF}$  bit of  $\text{RTC\_ISR}$  register is set (see [Section 17.6.4](#)). The copy is not performed in Stop and Standby mode. When exiting these modes, the shadow registers are updated after up to 2  $\text{RTCCLK}$  periods.

When the application reads the calendar registers, it accesses the content of the shadow registers. It is possible to make a direct access to the calendar registers by setting the  $\text{BYPHAD}$  control bit in the  $\text{RTC\_CR}$  register. By default, this bit is cleared, and the user accesses the shadow registers.

When reading the  $\text{RTC\_SSR}$ ,  $\text{RTC\_TR}$  or  $\text{RTC\_DR}$  registers in  $\text{BYPHAD}=0$  mode, the frequency of the  $\text{APB}$  clock ( $f_{\text{APB}}$ ) must be at least 7 times the frequency of the RTC clock ( $f_{\text{RTCCLK}}$ ).

The shadow registers are reset by system reset.

### 17.3.3 Programmable alarms

The RTC unit provides two programmable alarms, Alarm A and Alarm B.

The programmable alarm functions are enabled through the  $\text{ALRAIE}$  and  $\text{ALRBIE}$  bits in the  $\text{RTC\_CR}$  register. The  $\text{ALRAF}$  and  $\text{ALRBF}$  flags are set to 1 if the calendar subseconds, seconds, minutes, hours, date or day match the values programmed in the alarm registers  $\text{RTC\_ALRMSSR}/\text{RTC\_ALRMAR}$  and  $\text{RTC\_ALRMBSSR}/\text{RTC\_ALRMBR}$ , respectively. Each calendar field can be independently selected through the  $\text{MSKx}$  bits of the

RTC\_ALRMAR and RTC\_ALRMBR registers, and through the MASKSSx bits of the RTC\_ALRMASRR and RTC\_ALRMBSSR registers. The alarm interrupts are enabled through the ALRAIE and ALRBIE bits in the RTC\_CR register.

Alarm A and Alarm B (if enabled by bits OSEL[1:0] in RTC\_CR register) can be routed to the RTC\_ALARM output. RTC\_ALARM polarity can be configured through bit POL in the RTC\_CR register.

**Caution:** If the seconds field is selected (MSK0 bit reset in RTC\_ALRMAR or RTC\_ALRMBR), the synchronous prescaler division factor set in the RTC\_PRER register must be at least 3 to ensure correct behavior.

### 17.3.4 Periodic auto-wakeup

The periodic wakeup flag is generated by a 16-bit programmable auto-reload down-counter. The wakeup timer range can be extended to 17 bits.

The wakeup function is enabled through the WUTE bit in the RTC\_CR register.

The wakeup timer clock input can be:

- RTC clock (RTCCLK) divided by 2, 4, 8, or 16.  
When RTCCLK is LSE(32.768kHz), this allows to configure the wakeup interrupt period from 122  $\mu$ s to 32 s, with a resolution down to 61  $\mu$ s.
- ck\_spre (usually 1 Hz internal clock)  
When ck\_spre frequency is 1Hz, this allows to achieve a wakeup time from 1 s to around 36 hours with one-second resolution. This large programmable time range is divided in 2 parts:
  - from 1s to 18 hours when WUCKSEL [2:1] = 10
  - and from around 18h to 36h when WUCKSEL[2:1] = 11. In this last case 2<sup>16</sup> is added to the 16-bit counter current value. When the initialization sequence is complete (see [Programming the wakeup timer on page 433](#)), the timer starts counting down. When the wakeup function is enabled, the down-counting remains active in low-power modes. In addition, when it reaches 0, the WUTF flag is set in the RTC\_ISR register, and the wakeup counter is automatically reloaded with its reload value (RTC\_WUTR register value).

The WUTF flag must then be cleared by software.

When the periodic wakeup interrupt is enabled by setting the WUTIE bit in the RTC\_CR2 register, it can exit the device from low-power modes.

The periodic wakeup flag can be routed to the RTC\_ALARM output provided it has been enabled through bits OSEL[1:0] of RTC\_CR register. RTC\_ALARM polarity can be configured through the POL bit in the RTC\_CR register.

System reset, as well as low-power modes (Sleep, Stop and Standby) have no influence on the wakeup timer.

## 17.3.5 RTC initialization and configuration

### RTC register access

The RTC registers are 32-bit registers. The APB interface introduces 2 wait-states in RTC register accesses except on read accesses to calendar shadow registers when BYPSHAD=0.

### RTC register write protection

After system reset, the RTC registers are protected against parasitic write access with the DBP bit of the PWR power control register (PWR\_CR). The DBP bit must be set to enable RTC registers write access.

After backup domain reset, all the RTC registers are write-protected. Writing to the RTC registers is enabled by writing a key into the Write Protection register, RTC\_WPR.

The following steps are required to unlock the write protection on all the RTC registers except for RTC\_ISR[13:8], RTC\_TAFCR, and RTC\_BKPxR.

1. Write '0xCA' into the RTC\_WPR register.
2. Write '0x53' into the RTC\_WPR register.

Writing a wrong key reactivates the write protection.

The protection mechanism is not affected by system reset.

### Calendar initialization and configuration

To program the initial time and date calendar values, including the time format and the prescaler configuration, the following sequence is required:

1. Set INIT bit to 1 in the RTC\_ISR register to enter initialization mode. In this mode, the calendar counter is stopped and its value can be updated.
2. Poll INITF bit of in the RTC\_ISR register. The initialization phase mode is entered when INITF is set to 1. It takes from 1 to 2 RTCCLK clock cycles (due to clock synchronization).
3. To generate a 1 Hz clock for the calendar counter, program first the synchronous prescaler factor in RTC\_PRER register, and then program the asynchronous prescaler factor. Even if only one of the two fields needs to be changed, 2 separate write accesses must be performed to the RTC\_PRER register.
4. Load the initial time and date values in the shadow registers (RTC\_TR and RTC\_DR), and configure the time format (12 or 24 hours) through the FMT bit in the RTC\_CR register.
5. Exit the initialization mode by clearing the INIT bit. The actual calendar counter value is then automatically loaded and the counting restarts after 4 RTCCLK clock cycles.

When the initialization sequence is complete, the calendar starts counting.

*Note:* After a system reset, the application can read the INITS flag in the RTC\_ISR register to check if the calendar has been initialized or not. If this flag equals 0, the calendar has not been initialized since the year field is set at its backup domain reset default value (0x00). To read the calendar after initialization, the software must first check that the RSF flag is set in the RTC\_ISR register.

### Daylight saving time

The daylight saving time management is performed through bits SUB1H, ADD1H, and BKP of the RTC\_CR register.

Using SUB1H or ADD1H, the software can subtract or add one hour to the calendar in one single operation without going through the initialization procedure.

In addition, the software can use the BKP bit to memorize this operation.

### Programming the alarm

A similar procedure must be followed to program or update the programmable alarm (Alarm A or Alarm B):

1. Clear ALRAE or ALRBIE in RTC\_CR to disable Alarm A or Alarm B.
2. Poll ALRAWF or ALRBWF in RTC\_ISR until it is set to make sure the access to alarm registers is allowed. This takes 1 to 2 RTCCLK clock cycles (due to clock synchronization).
3. Program the Alarm A or Alarm B registers (RTC\_ALRMASR/RTC\_ALRMAR or RTC\_ALRMBSSR/RTC\_ALRMBR).
4. Set ALRAE or ALRBIE in the RTC\_CR register to enable Alarm A or Alarm B again.

*Note:* Each change of the RTC\_CR register is taken into account after 1 to 2 RTCCLK clock cycles due to clock synchronization.

### Programming the wakeup timer

The following sequence is required to configure or change the wakeup timer auto-reload value (WUT[15:0] in RTC\_WUTR):

1. Clear WUTE in RTC\_CR to disable the wakeup timer.
2. Poll WUTWF until it is set in RTC\_ISR to make sure the access to wakeup auto-reload counter and to WUCKSEL[2:0] bits is allowed. It takes 1 to 2 RTCCLK clock cycles (due to clock synchronization).
3. Program the wakeup auto-reload value WUT[15:0], and the wakeup clock selection (WUCKSEL[2:0] bits in RTC\_CR). Set WUTE in RTC\_CR to enable the timer again. The wakeup timer restarts down-counting.

## 17.3.6 Reading the calendar

To read the RTC calendar registers (RTC\_SSR, RTC\_TR and RTC\_DR) properly, the APB1 clock frequency ( $f_{PCLK1}$ ) must be equal to or greater than seven times the  $f_{RTCCLK}$  RTC clock frequency. This ensures a secure behavior of the synchronization mechanism.

If the APB1 clock frequency is less than seven times the RTC clock frequency, the software must read the calendar time and date registers twice. If the second read of the RTC\_TR gives the same result as the first read, this ensures that the data is correct. Otherwise a third read access must be done. In any case the APB1 clock frequency must never be lower than the RTC clock frequency.

The RSF bit is set in RTC\_ISR register each time the calendar registers are copied into the RTC\_SSR, RTC\_TR and RTC\_DR shadow registers. The copy is performed every two RTCCLK cycles. To ensure consistency between the 3 values, reading either RTC\_SSR or RTC\_TR locks the values in the higher-order calendar shadow registers until RTC\_DR is read. In case the software makes read accesses to the calendar in a time interval smaller

than 2 RTCCLK periods: RSF must be cleared by software after the first calendar read, and then the software must wait until RSF is set before reading again the RTC\_SSR, RTC\_TR and RTC\_DR registers.

After waking up from low-power mode (Stop or Standby), RSF must be cleared by software. The software must then wait until it is set again before reading the RTC\_SSR, RTC\_TR and RTC\_DR registers.

The RSF bit must be cleared after wakeup and not before entering low-power mode.

*Note:* After a system reset, the software must wait until RSF is set before reading the RTC\_SSR, RTC\_TR and RTC\_DR registers. Indeed, a system reset resets the shadow registers to their default values.

After an initialization (refer to [Calendar initialization and configuration on page 432](#)): the software must wait until RSF is set before reading the RTC\_SSR, RTC\_TR and RTC\_DR registers.

After synchronization (refer to [Section 17.3.8: RTC synchronization](#)): the software must wait until RSF is set before reading the RTC\_SSR, RTC\_TR and RTC\_DR registers.

### **When the BYPSHAD control bit is set in the RTC\_CR register (bypass shadow registers)**

Reading the calendar registers gives the values from the calendar counters directly, thus eliminating the need to wait for the RSF bit to be set. This is especially useful after exiting from low power modes (STOP or Standby), since the shadow registers are not updated during these modes.

When the BYPSHAD bit is set to 1, the results of the different registers might not be coherent with each other if an RTCCLK edge occurs between two read accesses to the registers. Additionally, the value of one of the registers may be incorrect if an RTCCLK edge occurs during the read operation. The software must read all the registers twice, and then compare the results to confirm that the data is coherent and correct. Alternatively, the software can just compare the two results of the least-significant calendar register.

*Note:* While BYPSHAD=1, instructions which read the calendar registers require one extra APB cycle to complete.

## **17.3.7 Resetting the RTC**

The calendar shadow registers (RTC\_SSR, RTC\_TR and RTC\_DR) and some bits of the RTC status register (RTC\_ISR) are reset to their default values by all available system reset sources.

On the contrary, the following registers are reset to their default values by a backup domain reset and are not affected by a system reset: the RTC current calendar registers, the RTC control register (RTC\_CR), the prescaler register (RTC\_PRER), the RTC calibration registers (RTC\_CALIBR or RTC\_CALR), the RTC shift register (RTC\_SHIFTR), the RTC timestamp registers (RTC\_TSSSR, RTC\_TSTR and RTC\_TSDR), the RTC tamper and alternate function configuration register (RTC\_TAFCR), the RTC backup registers (RTC\_BKPxR), the wakeup timer register (RTC\_WUTR), the Alarm A and Alarm B registers (RTC\_ALRMASR/RTC\_ALRMAR and RTC\_ALRMBSSR/RTC\_ALRMBR).

In addition, the RTC keeps on running under system reset if the reset source is different from a backup domain reset. When a backup domain reset occurs, the RTC is stopped and all the RTC registers are set to their reset values.

### 17.3.8 RTC synchronization

The RTC can be synchronized to a remote clock with a high degree of precision. After reading the sub-second field (RTC\_SSR or RTC\_TSSSR), a calculation can be made of the precise offset between the times being maintained by the remote clock and the RTC. The RTC can then be adjusted to eliminate this offset by “shifting” its clock by a fraction of a second using RTC\_SHIFTR.

RTC\_SSR contains the value of the synchronous prescaler’s counter. This allows one to calculate the exact time being maintained by the RTC down to a resolution of  $1 / (\text{PREDIV\_S} + 1)$  seconds. As a consequence, the resolution can be improved by increasing the synchronous prescaler value (PREDIV\_S[14:0]). The maximum resolution allowed (30.52  $\mu$ s with a 32768 Hz clock) is obtained with PREDIV\_S set to 0x7FFF.

However, increasing PREDIV\_S means that PREDIV\_A must be decreased in order to maintain the synchronous prescaler’s output at 1 Hz. In this way, the frequency of the asynchronous prescaler’s output increases, which may increase the RTC dynamic consumption.

The RTC can be finely adjusted using the RTC shift control register (RTC\_SHIFTR). Writing to RTC\_SHIFTR can shift (either delay or advance) the clock by up to a second with a resolution of  $1 / (\text{PREDIV\_S} + 1)$  seconds. The shift operation consists of adding the SUBFS[14:0] value to the synchronous prescaler counter SS[15:0]: this will delay the clock. If at the same time the ADD1S bit is set, this results in adding one second and at the same time subtracting a fraction of second, so this will advance the clock.

**Caution:** Before initiating a shift operation, the user must check that SS[15] = 0 in order to ensure that no overflow will occur.

As soon as a shift operation is initiated by a write to the RTC\_SHIFTR register, the SHPF flag is set by hardware to indicate that a shift operation is pending. This bit is cleared by hardware as soon as the shift operation has completed.

**Caution:** This synchronization feature is not compatible with the reference clock detection feature: firmware must not write to RTC\_SHIFTR when REFCKON=1.

### 17.3.9 RTC reference clock detection

The RTC calendar update can be synchronized to a reference clock RTC\_REFIN, usually the mains (50 or 60 Hz). The RTC\_REFIN reference clock should have a higher precision than the 32.768 kHz LSE clock. When the RTC\_REFIN detection is enabled (REFCKON bit of RTC\_CR set to 1), the calendar is still clocked by the LSE, and RTC\_REFIN is used to compensate for the imprecision of the calendar update frequency (1 Hz).

Each 1 Hz clock edge is compared to the nearest reference clock edge (if one is found within a given time window). In most cases, the two clock edges are properly aligned. When the 1 Hz clock becomes misaligned due to the imprecision of the LSE clock, the RTC shifts the 1 Hz clock a bit so that future 1 Hz clock edges are aligned. Thanks to this mechanism, the calendar becomes as precise as the reference clock.

The RTC detects if the reference clock source is present by using the 256 Hz clock (ck\_apre) generated from the 32.768 kHz quartz. The detection is performed during a time window around each of the calendar updates (every 1 s). The window equals 7 ck\_apre periods when detecting the first reference clock edge. A smaller window of 3 ck\_apre periods is used for subsequent calendar updates.



Each time the reference clock is detected in the window, the asynchronous prescaler which outputs the `ck_apre` clock is forced to reload. This has no effect when the reference clock and the 1 Hz clock are aligned because the prescaler is being reloaded at the same moment. When the clocks are not aligned, the reload shifts future 1 Hz clock edges a little for them to be aligned with the reference clock.

If the reference clock halts (no reference clock edge occurred during the 3 `ck_apre` window), the calendar is updated continuously based solely on the LSE clock. The RTC then waits for the reference clock using a large 7 `ck_apre` period detection window centered on the `ck_spre` edge.

When the reference clock detection is enabled, `PREDIV_A` and `PREDIV_S` must be set to their default values:

- `PREDIV_A = 0x007F`
- `PREDIV_S = 0x00FF`

*Note:* The reference clock detection is not available in Standby mode.

**Caution:** The reference clock detection feature cannot be used in conjunction with the coarse digital calibration: `RTC_CALIBR` must be kept at `0x0000 0000` when `REFCKON=1`.

### 17.3.10 RTC coarse digital calibration

Two digital calibration methods are available: coarse and smooth calibration. To perform coarse calibration refer to [Section 17.6.7: RTC calibration register \(RTC\\_CALIBR\)](#).

The two calibration methods are not intended to be used together, the application must select one of the two methods. Coarse calibration is provided for compatibility reasons. To perform smooth calibration refer to [Section 17.3.11: RTC smooth digital calibration](#) and the [Section 17.6.16: RTC calibration register \(RTC\\_CALR\)](#)

The coarse digital calibration can be used to compensate crystal inaccuracy by adding (positive calibration) or masking (negative calibration) clock cycles at the output of the asynchronous prescaler (`ck_apre`).

Positive and negative calibration are selected by setting the `DCS` bit in `RTC_CALIBR` register to '0' and '1', respectively.

When positive calibration is enabled (`DCS = '0'`), 2 `ck_apre` cycles are added every minute (around 15360 `ck_apre` cycles) for `2xDC` minutes. This causes the calendar to be updated sooner, thereby adjusting the effective RTC frequency to be a bit higher.

When negative calibration is enabled (`DCS = '1'`), 1 `ck_apre` cycle is removed every minute (around 15360 `ck_apre` cycles) for `2xDC` minutes. This causes the calendar to be updated later, thereby adjusting the effective RTC frequency to be a bit lower.

`DC` is configured through bits `DC[4:0]` of `RTC_CALIBR` register. This number ranges from 0 to 31 corresponding to a time interval (`2xDC`) ranging from 0 to 62.

The coarse digital calibration can be configured only in initialization mode, and starts when the `INIT` bit is cleared. The full calibration cycle lasts 64 minutes. The first `2xDC` minutes of the 64 -minute cycle are modified as just described.

Negative calibration can be performed with a resolution of about 2 ppm while positive calibration can be performed with a resolution of about 4 ppm. The maximum calibration ranges from -63 ppm to 126 ppm.

The calibration can be performed either on the LSE or on the HSE clock.

**Caution:** Digital calibration may not work correctly if `PREDIV_A < 6`.

### Case of `RTCCLK=32.768 kHz` and `PREDIV_A+1=128`

The following description assumes that `ck_apre` frequency is 256 Hz obtained with an LSE clock nominal frequency of 32.768 kHz, and `PREDIV_A` set to 127 (default value).

The `ck_spre` clock frequency is only modified during the first 2xDC minutes of the 64-minute cycle. For example, when DC equals 1, only the first 2 minutes are modified. This means that the first 2xDC minutes of each 64-minute cycle have, once per minute, one second either shortened by 256 or lengthened by 128 RTCCLK cycles, given that each `ck_apre` cycle represents 128 RTCCLK cycles (with `PREDIV_A+1=128`).

Therefore each calibration step has the effect of adding 512 or subtracting 256 oscillator cycles for every 125829120 RTCCLK cycles (64min x 60 s/min x 32768 cycles/s). This is equivalent to +4.069 ppm or -2.035 ppm per calibration step. As a result, the calibration resolution is +10.5 or -5.27 seconds per month, and the total calibration ranges from +5.45 to - 2.72 minutes per month.

In order to measure the clock deviation, a 512 Hz clock is output for calibration. Refer to [Section 17.3.14: Calibration clock output](#).

## 17.3.11 RTC smooth digital calibration

RTC frequency can be digitally calibrated with a resolution of about 0.954 ppm with a range from -487.1 ppm to +488.5 ppm. The correction of the frequency is performed using series of small adjustments (adding and/or subtracting individual RTCCLK pulses). These adjustments are fairly well distributed so that the RTC is well calibrated even when observed over short durations of time.

The smooth digital calibration is performed during a cycle of about  $2^{20}$  RTCCLK pulses, or 32 seconds when the input frequency is 32768 Hz. [This cycle is maintained by a 20-bit counter, `cal\_cnt\[19:0\]`, clocked by RTCCLK.](#)

The smooth calibration register (`RTC_CALR`) specifies the number of RTCCLK clock cycles to be masked during the 32-second cycle:

- Setting the bit `CALM[0]` to 1 causes exactly one pulse to be masked during the 32-second cycle.
- Setting `CALM[1]` to 1 causes two additional cycles to be masked
- Setting `CALM[2]` to 1 causes four additional cycles to be masked
- and so on up to `CALM[8]` set to 1 which causes 256 clocks to be masked.

*Note:* `CALM[8:0]` (`RTC_CALRx`) specifies the number of RTCCLK pulses to be masked during the 32-second cycle. Setting the bit `CALM[0]` to '1' causes exactly one pulse to be masked during the 32-second cycle [at the moment when `cal\_cnt\[19:0\]` is 0x80000](#); `CALM[1]=1` causes two other cycles to be masked [\(when `cal\_cnt` is 0x40000 and 0xC0000\)](#); `CALM[2]=1` causes four other cycles to be masked [\(`cal\_cnt` = 0x20000/0x60000/0xA0000/ 0xE0000\)](#); and so on up to `CALM[8]=1` which causes 256 clocks to be masked [\(`cal\_cnt` = 0xFF800\)](#).

While `CALM` allows the RTC frequency to be reduced by up to 487.1 ppm with fine resolution, the bit `CALP` can be used to increase the frequency by 488.5 ppm. Setting `CALP` to '1' effectively inserts an extra RTCCLK pulse every  $2^{11}$  RTCCLK cycles, which means that 512 clocks are added during every 32-second cycle.

Using CALM together with CALP, an offset ranging from -511 to +512 RTCCLK cycles can be added during the 32-second cycle, which translates to a calibration range of -487.1 ppm to +488.5 ppm with a resolution of about 0.954 ppm.

The formula to calculate the effective calibrated frequency ( $F_{CAL}$ ) given the input frequency ( $F_{RTCCLK}$ ) is as follows:

$$F_{CAL} = F_{RTCCLK} \times [1 + (CALP \times 512 - CALM) / (2^{20} + CALM - CALP \times 512)]$$

### Calibration when PREDIV\_A < 3

The CALP bit can not be set to 1 when the asynchronous prescaler value (PREDIV\_A bits in RTC\_PRER register) is less than 3. If CALP was already set to 1 and PREDIV\_A bits are set to a value less than 3, CALP is ignored and the calibration operates as if CALP was equal to 0.

To perform a calibration with PREDIV\_A less than 3, the synchronous prescaler value (PREDIV\_S) should be reduced so that each second is accelerated by 8 RTCCLK clock cycles, which is equivalent to adding 256 clock cycles every 32 seconds. As a result, between 255 and 256 clock pulses (corresponding to a calibration range from 243.3 to 244.1 ppm) can effectively be added during each 32-second cycle using only the CALM bits.

With a nominal RTCCLK frequency of 32768 Hz, when PREDIV\_A equals 1 (division factor of 2), PREDIV\_S should be set to 16379 rather than 16383 (4 less). The only other interesting case is when PREDIV\_A equals 0, PREDIV\_S should be set to 32759 rather than 32767 (8 less).

If PREDIV\_S is reduced in this way, the formula given the effective frequency of the calibrated input clock is as follows:

$$F_{CAL} = F_{RTCCLK} \times [1 + (256 - CALM) / (2^{20} + CALM - 256)]$$

In this case, CALM[7:0] equals 0x100 (the midpoint of the CALM range) is the correct setting if RTCCLK is exactly 32768.00 Hz.

### Verifying the RTC calibration

RTC precision is performed by measuring the precise frequency of RTCCLK and calculating the correct CALM value and CALP values. An optional 1 Hz output is provided to allow applications to measure and verify the RTC precision. Measuring the precise frequency of the RTC over a limited interval can result in a measurement error of up to 2 RTCCLK clock cycles over the measurement period, depending on how the digital calibration cycle is aligned with the measurement period.

However, this measurement error can be eliminated if the measurement period is the same length as the calibration cycle period. In this case, the only error observed is the error due to the resolution of the digital calibration.

- By default, the calibration cycle period is 32 seconds.  
Using this mode and measuring the accuracy of the 1 Hz output over exactly 32 seconds guarantees that the measure is within 0.477 ppm (0.5 RTCCLK cycles over 32 seconds, due to the limitation of the calibration resolution).
- CALW16 bit of the RTC\_CALR register can be set to 1 to force a 16-second calibration cycle period.  
In this case, the RTC precision can be measured during 16 seconds with a maximum error of 0.954 ppm (0.5 RTCCLK cycles over 16 seconds). However, since the

calibration resolution is reduced, the long term RTC precision is also reduced to 0.954 ppm: CALM[0] bit is stuck at 0 when CALW16 is set to 1.

- CALW8 bit of the RTC\_CALR register can be set to 1 to force a 8- second calibration cycle period.

In this case, the RTC precision can be measured during 8 seconds with a maximum error of 1.907 ppm (0.5 RTCCLK cycles over 8s). The long term RTC precision is also reduced to 1.907 ppm: CALM[1:0] bits are stuck at 00 when CALW8 is set to 1.

### Re-calibration on-the-fly

The calibration register (RTC\_CALR) can be updated on-the-fly while RTC\_ISR/INITF=0, by using the follow process:

1. Poll the RTC\_ISR/RECALPF (re-calibration pending flag).
2. If it is set to 0, write a new value to RTC\_CALR, if necessary. RECALPF is then automatically set to 1
3. Within three  $ck\_apre$  cycles after the write operation to RTC\_CALR, the new calibration settings take effect.

### 17.3.12 Timestamp function

Timestamp is enabled by setting the TSE bit of RTC\_CR register to 1.

The calendar is saved in the timestamp registers (RTC\_TSSSR, RTC\_TSTR, RTC\_TSDR) when a timestamp event is detected on the pin to which the TIMESTAMP additional function is mapped. When a timestamp event occurs, the timestamp flag bit (TSF) in RTC\_ISR register is set.

By setting the TSIE bit in the RTC\_CR register, an interrupt is generated when a timestamp event occurs.

If a new timestamp event is detected while the timestamp flag (TSF) is already set, the timestamp overflow flag (TSOVF) flag is set and the timestamp registers (RTC\_TSTR and RTC\_TSDR) maintain the results of the previous event.

*Note:* TSF is set 2  $ck\_apre$  cycles after the timestamp event occurs due to synchronization process.

*There is no delay in the setting of TSOVF. This means that if two timestamp events are close together, TSOVF can be seen as '1' while TSF is still '0'. As a consequence, it is recommended to poll TSOVF only after TSF has been set.*

**Caution:** If a timestamp event occurs immediately after the TSF bit is supposed to be cleared, then both TSF and TSOVF bits are set. To avoid masking a timestamp event occurring at the same moment, the application must not write '0' into TSF bit unless it has already read it to '1'.

Optionally, a tamper event can cause a timestamp to be recorded. See the description of the TAMPTS control bit in [Section 17.6.17: RTC tamper and alternate function configuration register \(RTC\\_TAFCR\)](#). If the timestamp event is on the same pin as a tamper event configured in filtered mode (TAMPFLT set to a non-zero value), the timestamp on tamper detection event mode must be selected by setting TAMPTS='1' in RTC\_TAFCR register.

### TIMESTAMP additional function

The TIMESTAMP additional function is mapped to RTC\_AF1.

### 17.3.13 Tamper detection

One tamper detection input is available. It can be configured either for edge detection, or for level detection with filtering.

#### RTC backup registers

The backup registers (RTC\_BKPxR) are twenty 32-bit registers for storing 80 bytes of user application data. They are implemented in the backup domain that remains powered-on by  $V_{BAT}$  when the  $V_{DD}$  power is switched off. They are not reset by system reset or when the device wakes up from Standby mode. They are reset by a backup domain reset

The backup registers are reset when a tamper detection event occurs (see [Section 17.6.20: RTC backup registers \(RTC\\_BKPxR\)](#) and [Tamper detection initialization on page 440](#)).

#### Tamper detection initialization

The tamper detection input is associated with the TAMP1F flag in the RTC\_ISR register. The input can be enabled by setting the TAMP1E bit to 1 in the RTC\_TAFPCR register.

A tamper detection event resets all backup registers (RTC\_BKPxR).

By setting the TAMPIE bit in the RTC\_TAFPCR register, an interrupt is generated when a tamper detection event occurs.

#### Timestamp on tamper event

With TAMPTS set to '1', any tamper event causes a timestamp to occur. In this case, either the TSF bit or the TSOVF bit are set in RTC\_ISR, in the same manner as if a normal timestamp event occurs. The tamper flag register (TAMP1F) is set at the same time that TSF or TSOVF is set.

#### Edge detection on tamper inputs

If the TAMPFLT bits are "00", the TAMPER pin generates tamper detection events (RTC\_TAMP[2:1]) when either a rising edge is observed or a falling edge is observed depending on the corresponding TAMPxTRG bit. The internal pull-up resistors on the TAMPER input are deactivated when edge detection is selected.

**Caution:** To avoid losing tamper detection events, the signal used for edge detection is logically ANDed with TAMPxE in order to detect a tamper detection event in case it occurs before the TAMPERx pin is enabled.

- When TAMPxTRG = 0: if the TAMPERx additional function is already high before tamper detection is enabled (TAMPxE bit set to 1), a tamper event is detected as soon as TAMPERx is enabled, even if there was no rising edge on TAMPERx after TAMPxE was set.
- When TAMPxTRG = 1: if the TAMPERx additional function is already low before tamper detection is enabled, a tamper event is detected as soon as TAMPERx is enabled (even if there was no falling edge on TAMPERx after TAMPxE was set).

After a tamper event has been detected and cleared, the TAMPERx additional function should be disabled and then re-enabled (TAMPxE set to 1) before re-programming the backup registers (RTC\_BKPxR). This prevents the application from writing to the backup registers while the TAMPERx value still indicates a tamper detection. This is equivalent to a level detection on the TAMPERx additional function.

*Note:* Tamper detection is still active when  $V_{DD}$  power is switched off. To avoid unwanted resetting of the backup registers, the pin to which the TAMPER additional function is mapped should be externally tied to the correct level.

### Level detection with filtering on tamper input

Level detection with filtering is performed by setting TAMPFLT to a non-zero value. A tamper detection event is generated when either 2, 4, or 8 (depending on TAMPFLT) consecutive samples are observed at the level designated by the TAMPxTRG bits (TAMP1TRG).

The TAMPER input is pre-charged through the I/O internal pull-up resistance before its state is sampled, unless disabled by setting TAMPPUDIS to 1. The duration of the precharge is determined by the TAMPPRCH bits, allowing for larger capacitances on the tamper inputs.

The trade-off between tamper detection latency and power consumption through the pull-up can be optimized by using TAMPFREQ to determine the frequency of the sampling for level detection.

*Note:* Refer to the datasheets for the electrical characteristics of the pull-up resistors.

### TAMPER additional function detection

The TAMPER1 additional function is mapped to the RTC\_AF1 pin.

## 17.3.14 Calibration clock output

When the COE bit is set to 1 in the RTC\_CR register, a reference clock is provided on the RTC\_CALIB device output. If the COSEL bit in the RTC\_CR register is reset and PREDIV\_A = 0x7F, the RTC\_CALIB frequency is  $f_{\text{RTCCLK}}/64$ . This corresponds to a calibration output at 512 Hz for an RTCCLK frequency at 32.768 kHz.

The RTC\_CALIB output is not impacted by the calibration value programmed in RTC\_CALIBR register. The RTC\_CALIB duty cycle is irregular: there is a light jitter on falling edges. It is therefore recommended to use rising edges.

If COSEL is set and "PREDIV\_S+1" is a non-zero multiple of 256 (i.e: PREDIV\_S[7:0] = 0xFF), the RTC\_CALIB frequency is  $f_{\text{RTCCLK}}/(256 * (\text{PREDIV\_A}+1))$ . This corresponds to a calibration output at 1 Hz for prescaler default values (PREDIV\_A = 0x7F, PREDIV\_S = 0xFF), with an RTCCLK frequency at 32.768 kHz.

### Calibration alternate function output

When the COE bit in the RTC\_CR register is set to 1, the calibration alternate function (RTC\_CALIB) is enabled on RTC\_OUT.

*Note:* When RTC\_CALIB or RTC\_ALARM is selected, RTC\_OUT is automatically configured in output alternate function.

## 17.3.15 Alarm output

Three functions can be selected on Alarm output: ALRAF. These functions reflect the contents of the corresponding flags in the RTC\_ISR register.

The OSEL[1:0] control bits in the RTC\_CR register are used to activate the alarm alternate function output (RTC\_ALARM) in RTC\_AF1, and to select the function which is output on RTC\_ALARM.

The polarity of the output is determined by the POL control bit in RTC\_CR so that the opposite of the selected flag bit is output when POL is set to 1.

**Alarm alternate function output**

RTC\_ALARM can be configured in output open drain or output push-pull using the control bit ALARMOUTTYPE in the RTC\_TAFCR register.

*Note: Once RTC\_ALARM is enabled, it has priority over RTC\_CALIB (COE bit is don't care on RTC\_AF1).  
When RTC\_CALIB or RTC\_ALARM is selected, RTC\_OUT is automatically configured in output alternate function.*

**17.4 RTC and low-power modes**

**Table 66. Effect of low-power modes on RTC**

Mode	Description
Sleep	No effect RTC interrupts cause the device to exit the Sleep mode.
Stop	The RTC remains active when the RTC clock source is LSE or LSI. RTC alarm, RTC tamper event, RTC time stamp event, and RTC Wakeup cause the device to exit the Stop mode.
Standby	The RTC remains active when the RTC clock source is LSE or LSI. RTC alarm, RTC tamper event, RTC time stamp event, and RTC Wakeup cause the device to exit the Standby mode.

**17.5 RTC interrupts**

All RTC interrupts are connected to the EXTI controller.

To enable the RTC Alarm interrupt, the following sequence is required:

1. Configure and enable the EXTI Line 17 in interrupt mode and select the rising edge sensitivity.
2. Configure and enable the RTC\_Alarm IRQ channel in the NVIC.
3. Configure the RTC to generate RTC alarms (Alarm A or Alarm B).

To enable the RTC Wakeup interrupt, the following sequence is required:

1. Configure and enable the EXTI Line 22 in interrupt mode and select the rising edge sensitivity.
2. Configure and enable the RTC\_WKUP IRQ channel in the NVIC.
3. Configure the RTC to generate the RTC wakeup timer event.

To enable the RTC Tamper interrupt, the following sequence is required:

1. Configure and enable the EXTI Line 21 in interrupt mode and select the rising edge sensitivity.
2. Configure and Enable the TAMP\_STAMP IRQ channel in the NVIC.
3. Configure the RTC to detect the RTC tamper event.

To enable the RTC TimeStamp interrupt, the following sequence is required:

1. Configure and enable the EXTI Line 21 in interrupt mode and select the rising edge sensitivity.
2. Configure and Enable the TAMP\_STAMP IRQ channel in the NVIC.
3. Configure the RTC to detect the RTC timestamp event.

**Table 67. Interrupt control bits**

Interrupt event	Event flag	Enable control bit	Exit the Sleep mode	Exit the Stop mode	Exit the Standby mode
Alarm A	ALRAF	ALRAIE	yes	yes <sup>(1)</sup>	yes <sup>(1)</sup>
Alarm B	ALRBF	ALRBIE	yes	yes <sup>(1)</sup>	yes <sup>(1)</sup>
Wakeup	WUTF	WUTIE	yes	yes <sup>(1)</sup>	yes <sup>(1)</sup>
TimeStamp	TSF	TSIE	yes	yes <sup>(1)</sup>	yes <sup>(1)</sup>
Tamper1 detection	TAMP1F	TAMPIE	yes	yes <sup>(1)</sup>	yes <sup>(1)</sup>

1. Wakeup from STOP and Standby modes is possible only when the RTC clock source is LSE or LSI.



## 17.6 RTC registers

Refer to [Section 1.1](#) of the reference manual for a list of abbreviations used in register descriptions.

The peripheral registers have to be accessed by words (32 bits).

### 17.6.1 RTC time register (RTC\_TR)

The RTC\_TR is the calendar time shadow register. This register must be written in initialization mode only. Refer to [Calendar initialization and configuration on page 432](#) and [Reading the calendar on page 433](#).

Address offset: 0x00

Backup domain reset value: 0x0000 0000

System reset: 0x0000 0000 when BYPSHAD = 0. Not affected when BYPSHAD = 1.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved									PM	HT[1:0]		HU[3:0]			
									rw	rw	rw	rw	rw	rw	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Res.	MNT[2:0]			MNU[3:0]				Res.	ST[2:0]			SU[3:0]			
	rw	rw	rw	rw	rw	rw	rw		rw	rw	rw	rw	rw	rw	rw

Bits 31-24 Reserved

Bit 23 Reserved, must be kept at reset value.

Bit 22 **PM**: AM/PM notation  
 0: AM or 24-hour format  
 1: PM

Bits 21:20 **HT[1:0]**: Hour tens in BCD format

Bits 19:16 **HU[3:0]**: Hour units in BCD format

Bit 15 Reserved, must be kept at reset value.

Bits 14:12 **MNT[2:0]**: Minute tens in BCD format

Bit 11:8 **MNU[3:0]**: Minute units in BCD format

Bit 7 Reserved, must be kept at reset value.

Bits 6:4 **ST[2:0]**: Second tens in BCD format

Bits 3:0 **SU[3:0]**: Second units in BCD format

*Note:* [This register is write protected. The write access procedure is described in RTC register write protection on page 432.](#)

### 17.6.2 RTC date register (RTC\_DR)

The RTC\_DR is the calendar date shadow register. This register must be written in initialization mode only. Refer to [Calendar initialization and configuration on page 432](#) and [Reading the calendar on page 433](#).

Address offset: 0x04

Backup domain reset value: 0x0000 2101

System reset: 0x0000 2101 when BYPSHAD = 0. Not affected when BYPSHAD = 1.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved								YT[3:0]				YU[3:0]			
								rw	rw	rw	rw	rw	rw	rw	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
WDU[2:0]			MT	MU[3:0]				Reserved		DT[1:0]		DU[3:0]			
rw	rw	rw	rw	rw	rw	rw	rw			rw	rw	rw	rw	rw	rw

Bits 31-24 Reserved

Bits 23:20 **YT[3:0]**: Year tens in BCD format

Bits 19:16 **YU[3:0]**: Year units in BCD format

Bits 15:13 **WDU[2:0]**: Week day units

000: forbidden

001: Monday

...

111: Sunday

Bit 12 **MT**: Month tens in BCD format

Bits 11:8 **MU**: Month units in BCD format

Bits 7:6 Reserved, must be kept at reset value.

Bits 5:4 **DT[1:0]**: Date tens in BCD format

Bits 3:0 **DU[3:0]**: Date units in BCD format

*Note:* This register is write protected. The write access procedure is described in [RTC register write protection on page 432](#).

### 17.6.3 RTC control register (RTC\_CR)

Address offset: 0x08

Backup domain reset value: 0x0000 0000

System reset: not affected

Reserved								COE	OSEL[1:0]		POL		BKP	SUB1H	ADD1H
								rw	rw	rw	rw	rw	rw	w	w
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
TSIE	WUTIE	ALRBIE	ALRAIE	TSE	WUTE	ALRBE	ALRAE	DCE	FMT	BYPSHAD	REFCKON	TSEDGE	WUCKSEL[2:0]		
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 31:24 Reserved, must be kept at reset value.

Bit 23 **COE**: Calibration output enable  
 This bit enables the RTC\_CALIB output  
 0: Calibration output disabled  
 1: Calibration output enabled

Bits 22:21 **OSEL[1:0]**: Output selection  
 These bits are used to select the flag to be routed to RTC\_ALARM output  
 00: Output disabled  
 01: Alarm A output enabled  
 10: Alarm B output enabled  
 11: Wakeup output enabled

Bit 20 **POL**: Output polarity  
 This bit is used to configure the polarity of RTC\_ALARM output  
 0: The pin is high when ALRAF/ALRBF/WUTF is asserted (depending on OSEL[1:0])  
 1: The pin is low when ALRAF/ALRBF/WUTF is asserted (depending on OSEL[1:0]).

Bit 19 **COSEL**: Calibration output selection  
 When COE=1, this bit selects which signal is output on RTC\_CALIB.  
 0: Calibration output is 512 Hz  
 1: Calibration output is 1 Hz  
 These frequencies are valid for RTCCLK at 32.768 kHz and prescalers at their default values (PREDIV\_A=127 and PREDIV\_S=255). Refer to [Section 17.3.14: Calibration clock output](#)

Bit 18 **BKP**: Backup  
 This bit can be written by the user to memorize whether the daylight saving time change has been performed or not.

Bit 17 **SUB1H**: Subtract 1 hour (winter time change)  
 When this bit is set outside initialization mode, 1 hour is subtracted to the calendar time if the current hour is not 0. This bit is always read as 0.  
 Setting this bit has no effect when current hour is 0.  
 0: No effect  
 1: Subtracts 1 hour to the current time. This can be used for winter time change.

- Bit 16 **ADD1H**: Add 1 hour (summer time change)  
When this bit is set outside initialization mode, 1 hour is added to the calendar time. This bit is always read as 0.  
0: No effect  
1: Adds 1 hour to the current time. This can be used for summer time change
- Bit 15 **TSIE**: Timestamp interrupt enable  
0: Timestamp Interrupt disable  
1: Timestamp Interrupt enable
- Bit 14 **WUTIE**: Wakeup timer interrupt enable  
0: Wakeup timer interrupt disabled  
1: Wakeup timer interrupt enabled
- Bit 13 **ALRBIE**: *Alarm B interrupt enable*  
0: Alarm B Interrupt disable  
1: Alarm B Interrupt enable
- Bit 12 **ALRAIE**: Alarm A interrupt enable  
0: Alarm A interrupt disabled  
1: Alarm A interrupt enabled
- Bit 11 **TSE**: Time stamp enable  
0: Time stamp disable  
1: Time stamp enable
- Bit 10 **WUTE**: Wakeup timer enable  
0: Wakeup timer disabled  
1: Wakeup timer enabled
- Bit 9 **ALRBE**: *Alarm B enable*  
0: Alarm B disabled  
1: Alarm B enabled
- Bit 8 **ALRAE**: Alarm A enable  
0: Alarm A disabled  
1: Alarm A enabled
- Bit 7 **DCE**: Coarse digital calibration enable  
0: Digital calibration disabled  
1: Digital calibration enabled  
PREDIV\_A must be 6 or greater
- Bit 6 **FMT**: Hour format  
0: 24 hour/day format  
1: AM/PM hour format
- Bit 5 **BYPSHAD**: Bypass the shadow registers  
0: Calendar values (when reading from RTC\_SSR, RTC\_TR, and RTC\_DR) are taken from the shadow registers, which are updated once every two RTCCLK cycles.  
1: Calendar values (when reading from RTC\_SSR, RTC\_TR, and RTC\_DR) are taken directly from the calendar counters.
- Note: If the frequency of the APB1 clock is less than seven times the frequency of RTCCLK, BYPSHAD must be set to '1'.*

Bit 4 **REFCKON**: Reference clock detection enable (50 or 60 Hz)

- 0: Reference clock detection disabled
- 1: Reference clock detection enabled

Note: *PREDIV\_S must be 0x00FF.*

Bit 3 **TSEDGE**: Timestamp event active edge

- 0: TIMESTAMP rising edge generates a timestamp event
  - 1: TIMESTAMP falling edge generates a timestamp event
- TSE must be reset when TSEDGE is changed to avoid unwanted TSF setting

Bits 2:0 **WUCKSEL[2:0]**: Wakeup clock selection

- 000: RTC/16 clock is selected
- 001: RTC/8 clock is selected
- 010: RTC/4 clock is selected
- 011: RTC/2 clock is selected
- 10x: ck\_spre (usually 1 Hz) clock is selected
- 11x: ck\_spre (usually 1 Hz) clock is selected and 2<sup>16</sup> is added to the WUT counter value (see note below)

Note: *WUT = Wakeup unit counter value. WUT = (0x0000 to 0xFFFF) + 0x10000 added when WUCKSEL[2:1 = 11].*

*Bits 7, 6 and 4 of this register can be written in initialization mode only (RTC\_ISR/INITF = 1).*

*Bits 2 to 0 of this register can be written only when RTC\_CR WUTE bit = 0 and RTC\_ISR WUTWF bit = 1.*

*It is recommended not to change the hour during the calendar hour increment as it could mask the incrementation of the calendar hour.*

*ADD1H and SUB1H changes are effective in the next second.*

*This register is write protected. The write access procedure is described in [RTC register write protection on page 432](#).*

### 17.6.4 RTC initialization and status register (RTC\_ISR)

Address offset: 0x0C

Backup domain reset value: 0x0000 0007

System reset value: Not affected except INIT, INITF and RSF which are cleared to 0.

Reserved															RECAL PF
															r
31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Res.	Res.	TAMP 1F	TSOVF	TSF	WUTF	ALRBF	ALRAF	INIT	INITF	RSF	INITS	SHPF	WUT WF	ALRB WF	ALRA WF
		rc_w0	rc_w0	rc_w0	rc_w0	rc_w0	rc_w0	rw	r	rc_w0	r	r	r	r	r

Bits 31:17 Reserved

Bit 16 **RECALPF**: Recalibration pending Flag

The RECALPF status flag is automatically set to '1' when software writes to the RTC\_CALR register, indicating that the RTC\_CALR register is blocked. When the new calibration settings are taken into account, this bit returns to '0'. Refer to [Section : Re-calibration on-the-fly](#).

Bits 15:14 Reserved, must be kept at reset value.

Bit 13 **TAMP1F**: Tamper detection flag

This flag is set by hardware when a tamper detection event is detected.  
It is cleared by software writing 0.

Bit 12 **TSOVF**: Timestamp overflow flag

This flag is set by hardware when a timestamp event occurs while TSF is already set.  
This flag is cleared by software by writing 0. It is recommended to check and then clear TSOVF only after clearing the TSF bit. Otherwise, an overflow might not be noticed if a timestamp event occurs immediately before the TSF bit is cleared.

Bit 11 **TSF**: Timestamp flag

This flag is set by hardware when a timestamp event occurs.  
This flag is cleared by software by writing 0.

Bit 10 **WUTF**: Wakeup timer flag

This flag is set by hardware when the wakeup auto-reload counter reaches 0.  
This flag is cleared by software by writing 0.  
This flag must be cleared by software at least 1.5 RTCCLK periods before WUTF is set to 1 again.

Bit 9 **ALRBF**: Alarm B flag

This flag is set by hardware when the time/date registers (RTC\_TR and RTC\_DR) match the Alarm B register (RTC\_ALRMBR).  
This flag is cleared by software by writing 0.

Bit 8 **ALRAF**: Alarm A flag

This flag is set by hardware when the time/date registers (RTC\_TR and RTC\_DR) match the Alarm A register (RTC\_ALRMAR).  
This flag is cleared by software by writing 0.

Bit 7 **INIT**: Initialization mode

0: Free running mode  
1: Initialization mode used to program time and date register (RTC\_TR and RTC\_DR), and prescaler register (RTC\_PRER). Counters are stopped and start counting from the new value when INIT is reset.

Bit 6 **INITF**: Initialization flag

When this bit is set to 1, the RTC is in initialization state, and the time, date and prescaler registers can be updated.

0: Calendar registers update is not allowed  
1: Calendar registers update is allowed.

Bit 5 **RSF**: Registers synchronization flag

This bit is set by hardware each time the calendar registers are copied into the shadow registers (RTC\_SSRx, RTC\_TRx and RTC\_DRx). This bit is cleared by hardware in initialization mode, while a shift operation is pending (SHPF=1), or when in bypass shadow register mode (BYPSHAD=1). This bit can also be cleared by software.

0: Calendar shadow registers not yet synchronized  
1: Calendar shadow registers synchronized

- Bit 4 **INITS**: Initialization status flag  
 This bit is set by hardware when the calendar year field is different from 0 (backup domain reset value state).  
 0: Calendar has not been initialized  
 1: Calendar has been initialized
- Bit 3 **SHPF**: Shift operation pending  
 0: No shift operation is pending  
 1: A shift operation is pending  
 This flag is set by hardware as soon as a shift operation is initiated by a write to the RTC\_SHIFTR. It is cleared by hardware when the corresponding shift operation has been executed. Writing to SHPF has no effect.
- Bit 2 **WUTWF**: Wakeup timer write flag  
 This bit is set by hardware when the wakeup timer values can be changed, after the WUTE bit has been set to 0 in RTC\_CR.  
 0: Wakeup timer configuration update not allowed  
 1: Wakeup timer configuration update allowed
- Bit 1 **ALRBWF**: Alarm B write flag  
 This bit is set by hardware when Alarm B values can be changed, after the ALRBIE bit has been set to 0 in RTC\_CR.  
 It is cleared by hardware in initialization mode.  
 0: Alarm B update not allowed  
 1: Alarm B update allowed.
- Bit 0 **ALRAWF**: Alarm A write flag  
 This bit is set by hardware when Alarm A values can be changed, after the ALRAE bit has been set to 0 in RTC\_CR.  
 It is cleared by hardware in initialization mode.  
 0: Alarm A update not allowed  
 1: Alarm A update allowed

*Note:* The ALRAF, ALRBF, WUTF and TSF bits are cleared 2 APB clock cycles after programming them to 0.

*This register is write protected (except for RTC\_ISR[13:8] bits). The write access procedure is described in [RTC register write protection on page 432](#).*

### 17.6.5 RTC prescaler register (RTC\_PRER)

Address offset: 0x10

Backup domain reset value: 0x007F 00FF

System reset: not affected

	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
	Reserved									PREDIV_A[6:0]						
										rw	rw	rw	rw	rw	rw	rw
	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Res.	PREDIV_S[14:0]															
	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw



Bits 31:24 Reserved

Bit 23 Reserved, must be kept at reset value.

Bits 22:16 **PREDIV\_A[6:0]**: Asynchronous prescaler factor

This is the asynchronous division factor:

$$ck\_apre\ frequency = RTCCLK\ frequency / (PREDIV\_A + 1)$$

Bit 15 Reserved, must be kept at reset value.

Bits 14:0 **PREDIV\_S[14:0]**: Synchronous prescaler factor

This is the synchronous division factor:

$$ck\_spre\ frequency = ck\_apre\ frequency / (PREDIV\_S + 1)$$

*Note:* This register must be written in initialization mode only. The initialization must be performed in two separate write accesses. Refer to [Calendar initialization and configuration on page 432](#)

*This register is write protected. The write access procedure is described in [RTC register write protection on page 432](#).*

### 17.6.6 RTC wakeup timer register (RTC\_WUTR)

Address offset: 0x14

Backup domain reset value: 0x0000 FFFF

System reset: not affected

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved															
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
WUT[15:0]															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 31:16 Reserved

Bits 15:0 **WUT[15:0]**: Wakeup auto-reload value bits

When the wakeup timer is enabled (WUTE set to 1), the WUTF flag is set every (WUT[15:0] + 1) ck\_wut cycles. The ck\_wut period is selected through WUCKSEL[2:0] bits of the RTC\_CR register

When WUCKSEL[2] = 1, the wakeup timer becomes 17-bits and WUCKSEL[1] effectively becomes WUT[16] the most-significant bit to be reloaded into the timer.

*Note:* The first assertion of WUTF occurs (WUT+1) ck\_wut cycles after WUTE is set. Setting WUT[15:0] to 0x0000 with WUCKSEL[2:0] = 011 (RTCCLK/2) is forbidden.

*Note:* This register can be written only when WUTWF is set to 1 in RTC\_ISR.

*This register is write protected. The write access procedure is described in [RTC register write protection on page 432](#).*

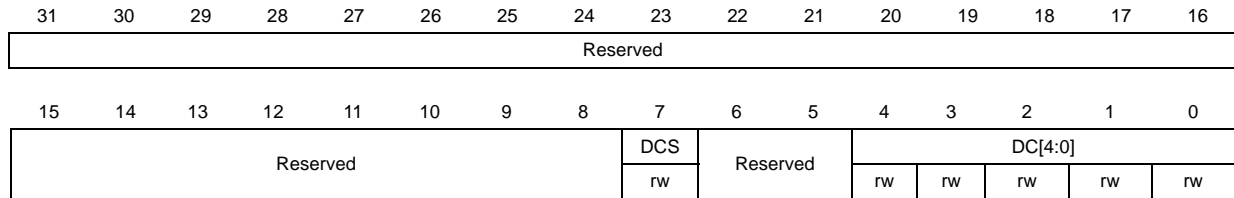


### 17.6.7 RTC calibration register (RTC\_CALIBR)

Address offset: 0x18

Backup domain reset value: 0x0000 0000

System reset: not affected



Bits 31:8 Reserved

Bit 7 **DCS**: Digital calibration sign

0: Positive calibration: calendar update frequency is increased

1: Negative calibration: calendar update frequency is decreased

Bits 6:5 Reserved, must be kept at reset value.

Bits 4:0 **DC[4:0]**: Digital calibration

DCS = 0 (positive calibration)

00000: + 0 ppm

00001: + 4 ppm (rounded value)

00010: + 8 ppm (rounded value)

..

11111: + 126 ppm (rounded value)

DCS = 1 (negative calibration)

00000: - 0 ppm

00001: - 2 ppm (rounded value)

00010: - 4 ppm (rounded value)

..

11111: - 63 ppm (rounded value)

Refer to [Case of RTCCLK=32.768 kHz and PREDIV\\_A+1=128 on page 437](#) for the exact step value.

*Note:* This register can be written in initialization mode only (RTC\_ISR/INITF = '1').

*This register is write protected. The write access procedure is described in [RTC register write protection on page 432](#).*

### 17.6.8 RTC alarm A register (RTC\_ALRMAR)

Address offset: 0x1C

Backup domain reset value: 0x0000 0000

System reset: not affected

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
MSK4	WDSEL	DT[1:0]		DU[3:0]				MSK3	PM	HT[1:0]		HU[3:0]			
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
MSK2	MNT[2:0]			MNU[3:0]				MSK1	ST[2:0]			SU[3:0]			
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bit 31 **MSK4**: Alarm A date mask  
 0: Alarm A set if the date/day match  
 1: Date/day don't care in Alarm A comparison

Bit 30 **WDSEL**: Week day selection  
 0: DU[3:0] represents the date units  
 1: DU[3:0] represents the week day. DT[1:0] is don't care.

Bits 29:28 **DT[1:0]**: Date tens in BCD format.

Bits 27:24 **DU[3:0]**: Date units or day in BCD format.

Bit 23 **MSK3**: Alarm A hours mask  
 0: Alarm A set if the hours match  
 1: Hours don't care in Alarm A comparison

Bit 22 **PM**: AM/PM notation  
 0: AM or 24-hour format  
 1: PM

Bits 21:20 **HT[1:0]**: Hour tens in BCD format.

Bits 19:16 **HU[3:0]**: Hour units in BCD format.

Bit 15 **MSK2**: Alarm A minutes mask  
 0: Alarm A set if the minutes match  
 1: Minutes don't care in Alarm A comparison

Bits 14:12 **MNT[2:0]**: Minute tens in BCD format.

Bits 11:8 **MNU[3:0]**: Minute units in BCD format.

Bit 7 **MSK1**: Alarm A seconds mask  
 0: Alarm A set if the seconds match  
 1: Seconds don't care in Alarm A comparison

Bits 6:4 **ST[2:0]**: Second tens in BCD format.

Bits 3:0 **SU[3:0]**: Second units in BCD format.

*Note:* This register can be written only when ALRAWF is set to 1 in RTC\_ISR, or in initialization mode.

This register is write protected. The write access procedure is described in [RTC register write protection on page 432](#).



### 17.6.9 RTC alarm B register (RTC\_ALRMBR)

Address offset: 0x20

Backup domain reset value: 0x0000 0000

System reset: not affected

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
MSK4	WDSEL	DT[1:0]		DU[3:0]				MSK3	PM	HT[1:0]		HU[3:0]			
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
MSK2	MNT[2:0]			MNU[3:0]				MSK1	ST[2:0]		SU[3:0]				
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

- Bit 31 **MSK4**: Alarm B date mask
  - 0: Alarm B set if the date and day match
  - 1: Date and day don't care in Alarm B comparison
- Bit 30 **WDSEL**: Week day selection
  - 0: DU[3:0] represents the date units
  - 1: DU[3:0] represents the week day. DT[1:0] is don't care.
- Bits 29:28 **DT[1:0]**: Date tens in BCD format
- Bits 27:24 **DU[3:0]**: Date units or day in BCD format
  - Bit 23 **MSK3**: Alarm B hours mask
    - 0: Alarm B set if the hours match
    - 1: Hours don't care in Alarm B comparison
  - Bit 22 **PM**: AM/PM notation
    - 0: AM or 24-hour format
    - 1: PM
- Bits 21:20 **HT[1:0]**: Hour tens in BCD format
- Bits 19:16 **HU[3:0]**: Hour units in BCD format
  - Bit 15 **MSK2**: Alarm B minutes mask
    - 0: Alarm B set if the minutes match
    - 1: Minutes don't care in Alarm B comparison
- Bits 14:12 **MNT[2:0]**: Minute tens in BCD format
- Bits 11:8 **MNU[3:0]**: Minute units in BCD format
  - Bit 7 **MSK1**: Alarm B seconds mask
    - 0: Alarm B set if the seconds match
    - 1: Seconds don't care in Alarm B comparison
- Bits 6:4 **ST[2:0]**: Second tens in BCD format
- Bits 3:0 **SU[3:0]**: Second units in BCD format



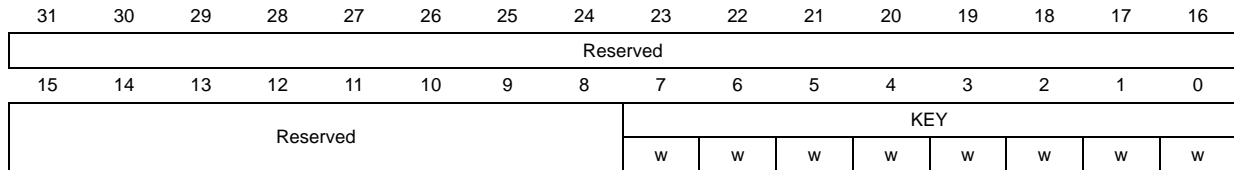
Note: This register can be written only when ALRBWF is set to 1 in RTC\_ISR, or in initialization mode.

This register is write protected. The write access procedure is described in [RTC register write protection on page 432](#).

### 17.6.10 RTC write protection register (RTC\_WPR)

Address offset: 0x24

Backup domain reset value: 0x0000 0000



Bits 31:8 Reserved, must be kept at reset value.

Bits 7:0 **KEY**: Write protection key

This byte is written by software.

Reading this byte always returns 0x00.

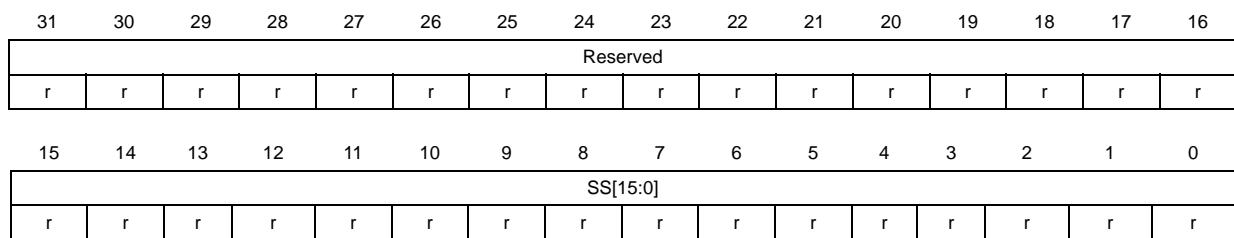
Refer to [RTC register write protection](#) for a description of how to unlock RTC register write protection.

### 17.6.11 RTC sub second register (RTC\_SSR)

Address offset: 0x28

Backup domain reset value: 0x0000 0000

System reset: 0x0000 0000 when BYPSHAD = 0. Not affected when BYPSHAD = 1.



Bits 31:16 Reserved

Bits 15:0 **SS**: Sub second value

SS[15:0] is the value in the synchronous prescaler's counter. The fraction of a second is given by the formula below:

$$\text{Second fraction} = ( \text{PREDIV\_S} - \text{SS} ) / ( \text{PREDIV\_S} + 1 )$$

Note: SS can be larger than PREDIV\_S only after a shift operation. In that case, the correct time/date is one second less than as indicated by RTC\_TR/RTC\_DR.

### 17.6.12 RTC shift control register (RTC\_SHIFTR)

Address offset: 0x2C

Backup domain reset value: 0x0000 0000

System reset: not affected

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
ADD1S	Reserved														
w	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Res.	SUBFS[14:0]														
r	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w

Bit 31 **ADD1S**: Add one second

0: No effect

1: Add one second to the clock/calendar

This bit is write only and is always read as zero. Writing to this bit has no effect when a shift operation is pending (when SHPF=1, in RTC\_ISR).

This function is intended to be used with SUBFS (see description below) in order to effectively add a fraction of a second to the clock in an atomic operation.

Bits 30:15 Reserved

Bits 14:0 **SUBFS**: Subtract a fraction of a second

These bits are write only and is always read as zero. Writing to this bit has no effect when a shift operation is pending (when SHPF=1, in RTC\_ISR).

The value which is written to SUBFS is added to the synchronous prescaler's counter. Since this counter counts down, this operation effectively subtracts from (delays) the clock by:

$$\text{Delay (seconds)} = \text{SUBFS} / (\text{PREDIV\_S} + 1)$$

A fraction of a second can effectively be added to the clock (advancing the clock) when the ADD1S function is used in conjunction with SUBFS, effectively advancing the clock by:

$$\text{Advance (seconds)} = ( 1 - ( \text{SUBFS} / ( \text{PREDIV\_S} + 1 ) ) )$$

*Note: Writing to SUBFS causes RSF to be cleared. Software can then wait until RSF=1 to be sure that the shadow registers have been updated with the shifted time.*

Refer to [Section 17.3.8: RTC synchronization](#).

*Note: This register is write protected. The write access procedure is described in [RTC register write protection on page 432](#)*

### 17.6.13 RTC time stamp time register (RTC\_TSTR)

Address offset: 0x30

Backup domain reset value: 0x0000 0000

System reset: not affected

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	
Reserved									PM	HT[1:0]			HU[3:0]			
									r	r	r	r	r	r	r	

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Res.	MNT[2:0]			MNU[3:0]				Res.	ST[2:0]			SU[3:0]			
	r	r	r	r	r	r	r		r	r	r	r	r	r	r

Bits 31:23 Reserved, must be kept at reset value.

Bit 22 **PM**: AM/PM notation  
 0: AM or 24-hour format  
 1: PM

Bits 21:20 **HT[1:0]**: Hour tens in BCD format.

Bits 19:16 **HU[3:0]**: Hour units in BCD format.

Bit 15 Reserved, must be kept at reset value.

Bits 14:12 **MNT[2:0]**: Minute tens in BCD format.

Bits 11:8 **MNU[3:0]**: Minute units in BCD format.

Bit 7 Reserved, must be kept at reset value.

Bits 6:4 **ST[2:0]**: Second tens in BCD format.

Bits 3:0 **SU[3:0]**: Second units in BCD format.

*Note:* The content of this register is valid only when TSF is set to 1 in RTC\_ISR. It is cleared when TSF bit is reset.

### 17.6.14 RTC time stamp date register (RTC\_TSDR)

Address offset: 0x34

Backup domain reset value: 0x0000 0000

System reset: not affected

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved															
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
WDU[1:0]			MT	MU[3:0]				Reserved	DT[1:0]		DU[3:0]				
r	r	r	r	r	r	r	r		r	r	r	r	r	r	

Bits 31:16 Reserved, must be kept at reset value.

Bits 15:13 **WDU[1:0]**: Week day units

Bit 12 **MT**: Month tens in BCD format

Bits 11:8 **MU[3:0]**: Month units in BCD format

Bits 7:6 Reserved, must be kept at reset value.

Bits 5:4 **DT[1:0]**: Date tens in BCD format

Bit 3:0 **DU[3:0]**: Date units in BCD format

*Note:* The content of this register is valid only when TSF is set to 1 in RTC\_ISR. It is cleared when TSF bit is reset.



### 17.6.15 RTC timestamp sub second register (RTC\_TSSSR)

Address offset: 0x38

Backup domain reset value: 0x0000 0000

System reset: not affected

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved															
r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
SS[15:0]															
r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r

Bits 31:16 Reserved

Bits 15:0 **SS**: Sub second value

SS[15:0] is the value of the synchronous prescaler's counter when the timestamp event occurred.

*Note:* The content of this register is valid only when RTC\_ISR/TSF is set. It is cleared when the RTC\_ISR/TSF bit is reset.

### 17.6.16 RTC calibration register (RTC\_CALR)

Address offset: 0x3C

Backup domain reset value: 0x0000 0000

System reset: not affected

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved															
r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
CALP	CALW8	CALW16	Reserved				CALM[8:0]								
rw	rw	rw	r	r	r	r	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 31:16 Reserved

Bit 15 **CALP**: Increase frequency of RTC by 488.5 ppm

0: No RTCCLK pulses are added.

1: One RTCCLK pulse is effectively inserted every  $2^{11}$  pulses (frequency increased by 488.5 ppm).

This feature is intended to be used in conjunction with CALM, which lowers the frequency of the calendar with a fine resolution. If the input frequency is 32768 Hz, the number of RTCCLK pulses added during a 32-second window is calculated as follows:  $(512 * CALP) - CALM$ .

Refer to [Section 17.3.11: RTC smooth digital calibration](#).

Bit 14 **CALW8**: Use an 8-second calibration cycle period

When CALW8 is set to '1', the 8-second calibration cycle period is selected.

CALM[1:0] are stuck at "00" when CALW8='1'.

Refer to [Section 17.3.11: RTC smooth digital calibration](#).

Bit 13 **CALW16**: Use a 16-second calibration cycle period

When CALW16 is set to '1', the 16-second calibration cycle period is selected. This bit must not be set to '1' if CALW8=1.

*Note: CALM[0] is stuck at '0' when CALW16='1'.*

Refer to [Section 17.3.11: RTC smooth digital calibration](#).

Bits 12:9 Reserved

Bits 8:0 **CALM[8:0]**: Calibration minus

The frequency of the calendar is reduced by masking CALM out of  $2^{20}$  RTCCLK pulses (32 seconds if the input frequency is 32768 Hz). This decreases the frequency of the calendar with a resolution of 0.9537 ppm.

To increase the frequency of the calendar, this feature should be used in conjunction with CALP.

See [Section 17.3.11: RTC smooth digital calibration on page 437](#).

*Note: This register is write protected. The write access procedure is described in [RTC register write protection on page 432](#)*



### 17.6.17 RTC tamper and alternate function configuration register (RTC\_TAFCR)

Address offset: 0x40

Backup domain reset value: 0x0000 0000

System reset: not affected

Reserved													ALARMOUT TYPE	TSIN SEL	TAMP1 INSEL
													rw	rw	rw
31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved													TAMPIE	TAMP1 TRG	TAMP1 E
													rw	rw	rw
TAMP- PUDIS		TAMP- PRCH[1:0]		TAMPFLT[1:0]		TAMPFREQ[2:0]			TAMPT S	Reserved					
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw				rw	rw	rw

Bits 31:19 Reserved. Always read as 0.

Bit 18 **ALARMOUTTYPE**: RTC\_ALARM output type

- 0: RTC\_ALARM is an open-drain output
- 1: RTC\_ALARM is a push-pull output

Bit 17 **TSINSEL**: TIMESTAMP mapping

- 0: RTC\_AF1 used as TIMESTAMP
- 1: Reserved

Bit 16 **TAMP1INSEL**: TAMPER1 mapping

- 0: RTC\_AF1 used as TAMPER1
- 1: Reserved

Bit 15 **TAMPPUDIS**: TAMPER pull-up disable

This bit determines if each of the tamper pins are pre-charged before each sample.

- 0: Precharge tamper pins before sampling (enable internal pull-up)
- 1: Disable precharge of tamper pins

Note:

Bits 14:13 **TAMPPRCH[1:0]**: Tamper precharge duration

These bit determines the duration of time during which the pull-up/is activated before each sample. TAMPPRCH is valid for each of the tamper inputs.

- 0x0: 1 RTCCLK cycle
- 0x1: 2 RTCCLK cycles
- 0x2: 4 RTCCLK cycles
- 0x3: 8 RTCCLK cycles

Bits 12:11 **TAMPFLT[1:0]**: Tamper filter count

These bits determines the number of consecutive samples at the specified level (TAMP\*TRG) necessary to activate a Tamper event. TAMPFLT is valid for each of the tamper inputs.

- 0x0: Tamper is activated on edge of tamper input transitions to the active level (no internal pull-up on tamper input).
- 0x1: Tamper is activated after 2 consecutive samples at the active level.
- 0x2: Tamper is activated after 4 consecutive samples at the active level.
- 0x3: Tamper is activated after 8 consecutive samples at the active level.



Bits 31:28 Reserved

Bits 27:24 **MASKSS[3:0]**: Mask the most-significant bits starting at this bit

0: No comparison on sub seconds for Alarm A. The alarm is set when the seconds unit is incremented (assuming that the rest of the fields match).

1: SS[14:1] are don't care in Alarm A comparison. Only SS[0] is compared.

2: SS[14:2] are don't care in Alarm A comparison. Only SS[1:0] are compared.

3: SS[14:3] are don't care in Alarm A comparison. Only SS[2:0] are compared.

...

12: SS[14:12] are don't care in Alarm A comparison. SS[11:0] are compared.

13: SS[14:13] are don't care in Alarm A comparison. SS[12:0] are compared.

14: SS[14] is don't care in Alarm A comparison. SS[13:0] are compared.

15: All 15 SS bits are compared and must match to activate alarm.

The overflow bits of the synchronous counter (bits 15) is never compared. This bit can be different from 0 only after a shift operation.

Bits 23:15 Reserved

Bits 14:0 **SS[14:0]**: Sub seconds value

This value is compared with the contents of the synchronous prescaler's counter to determine if Alarm A is to be activated. Only bits 0 up MASKSS-1 are compared.

*Note:* This register can be written only when ALRAE is reset in RTC\_CR register, or in initialization mode.

This register is write protected. The write access procedure is described in [RTC register write protection on page 432](#)

### 17.6.19 RTC alarm B sub second register (RTC\_ALRMBSSR)

Address offset: 0x48

Backup domain reset value: 0x0000 0000

System reset: not affected

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved				MASKSS[3:0]				Reserved							
r	r	r	r	rw	rw	rw	rw	r	r	r	r	r	r	r	r
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved	SS[14:0]														
r	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	w	rw	rw

Bits 31:28 Reserved

Bits 27:24 **MASKSS[3:0]**: Mask the most-significant bits starting at this bit

0x0: No comparison on sub seconds for Alarm B. The alarm is set when the seconds unit is incremented (assuming that the rest of the fields match).

0x1: SS[14:1] are don't care in Alarm B comparison. Only SS[0] is compared.

0x2: SS[14:2] are don't care in Alarm B comparison. Only SS[1:0] are compared.

0x3: SS[14:3] are don't care in Alarm B comparison. Only SS[2:0] are compared.

...

0xC: SS[14:12] are don't care in Alarm B comparison. SS[11:0] are compared.

0xD: SS[14:13] are don't care in Alarm B comparison. SS[12:0] are compared.

0xE: SS[14] is don't care in Alarm B comparison. SS[13:0] are compared.

0xF: All 15 SS bits are compared and must match to activate alarm.

The overflow bits of the synchronous counter (bits 15) is never compared. This bit can be different from 0 only after a shift operation.

Bits 23:15 Reserved

Bits 14:0 **SS[14:0]**: Sub seconds value

This value is compared with the contents of the synchronous prescaler's counter to determine if Alarm B is to be activated. Only bits 0 up to MASKSS-1 are compared.

*Note:* This register can be written only when ALRBIE is reset in RTC\_CR register, or in initialization mode.

*This register is write protected. The write access procedure is described in [Section : RTC register write protection](#)*

### 17.6.20 RTC backup registers (RTC\_BKPxR)

Address offset: 0x50 to 0x9C

Backup domain reset value: 0x0000 0000

System reset: not affected

BKP[31:16]															
31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw
BKP[15:0]															
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	w	rw	rw

Bits 31:0 BKP[31:0]

The application can write or read data to and from these registers.

They are powered-on by V<sub>BAT</sub> when V<sub>DD</sub> is switched off, so that they are not reset by System reset, and their contents remain valid when the device operates in low-power mode. This register is reset on a tamper detection event, as long as TAMPx<sub>F</sub>=1

### 17.6.21 RTC register map

Table 68. RTC register map and reset values

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0					
0x00	RTC_TR	Reserved										PM	HT [1:0]		HU[3:0]			Reserved	MNT[2:0]		MNU[3:0]			Reserved	ST[2:0]		SU[3:0]											
	Reset value											0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0			
0x04	RTC_DR	Reserved										YT[3:0]			YU[3:0]			WDU[2:0]		MT	MU[3:0]			Reserved	DT [1:0]		DU[3:0]											
	Reset value																	0	0	1	0	0	0	0	0	1	0	0	0	0	0	0	0	0	1			
0x08	RTC_CR	Reserved										COE	OSEL [1:0]		POL	COSEL	BKP	SUB1H	ADD1H	TSIE	WUTIE	ALRBIE	ALRAIE	TSE	WUTE	ALRBE	ALRAE	DCE	FMT	BYPHAD	REFCKON	TSEDGE	WCKSEL [2:0]					
	Reset value											0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0				
0x0C	RTC_ISR	Reserved																				TAMP1F	TSOVF	TSF	WUTF	ALRBF	ALRAF	INIT	INITF	RSF	INITS	SHPF	WUTWF	ALRBF	ALRAWF			
	Reset value																					0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x10	RTC_PRER	Reserved										PREDIV_A[6:0]						Reserved	PREDIV_S[14:0]																			
	Reset value											1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x14	RTC_WUTR	Reserved										WUT[15:0]																										
	Reset value											1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1			
0x18	RTC_CALIBR	Reserved																				DCS	Reserved	DC[4:0]														
	Reset value																					0	0	0														



Table 68. RTC register map and reset values (continued)

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0																			
0x1C	RTC_ALRMAR	MSK4	WDSEL	DT [1:0]	DU[3:0]			MSK3	PM	HT [1:0]	HU[3:0]			MSK2	MNT[2:0]		MNU[3:0]			MSK1	ST[2:0]		SU[3:0]																													
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0																			
0x20	RTC_ALRMBR	MSK4	WDSEL	DT [1:0]	DU[3:0]			MSK3	PM	HT [1:0]	HU[3:0]			MSK2	MNT[2:0]		MNU[3:0]			MSK2	ST[2:0]		SU[3:0]																													
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0																			
0x24	RTC_WPR	Reserved																							KEY[7:0]																											
	Reset value																								0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x28	RTC_SSR	Reserved												SS[15:0]																																						
	Reset value													0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0												
0x30	RTC_TSTR	Reserved								PM	HT [1:0]	HU[3:0]			Reserved	MNT[2:0]		MNU[3:0]			Reserved	ST[2:0]		SU[3:0]																												
	Reset value									0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0																
0x38	RTC_TSSSR	Reserved												SS[15:0]																																						
	Reset value													0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0											
0x3C	RTC_CALR	Reserved												CALP	CALW8	CALW16	Reserved			CALM[8:0]																																
	Reset value													0	0	0				0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0													
0x40	RTC_TAFCR	Reserved												ALARMOUTTYPE	TSINSEL	TAMP1INSEL	TAMPPUDIS	TAMPPRCH[1:0]	TAMPFLT[1:0]	TAMPFREQ[2:0]	TAMPPTS	Reserved			TAMPIE	TAMP1ETRIG	TAMP1E																									
	Reset value													0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0										
0x44	RTC_ALRMASSR	Reserved			MASKSS[3:0]			Reserved					SS[14:0]																																							
	Reset value				0	0	0	0						0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0																		
0x48	RTC_ALRMBSSR	Reserved			MASKSS[3:0]			Reserved					SS[14:0]																																							
	Reset value				0	0	0	0						0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0																		
0x50 to 0x9C	RTC_BKP0R	BKP[31:0]																																																		
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0																			
	to RTC_BKP19R	BKP[31:0]																																																		
Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0																			

Refer to [Table 1 on page 38](#) for the register boundary addresses.

**Caution:** In [Table 68](#), the reset value is the value after a backup domain reset. The majority of the registers are not affected by a system reset. For more information, please refer to [Section 17.3.7: Resetting the RTC](#).



## 18 Inter-integrated circuit (I<sup>2</sup>C) interface

### 18.1 I<sup>2</sup>C introduction

I<sup>2</sup>C (inter-integrated circuit) bus Interface serves as an interface between the microcontroller and the serial I<sup>2</sup>C bus. It provides multimaster capability, and controls all I<sup>2</sup>C bus-specific sequencing, protocol, arbitration and timing. It supports the standard mode (Sm, up to 100 kHz) and Fm mode (Fm, up to 400 kHz). The I<sup>2</sup>C bus frequency can be increased up to 1 MHz. For more details about the complete solution, please contact your local ST sales representative.

It may be used for a variety of purposes, including CRC generation and verification, SMBus (system management bus) and PMBus (power management bus).

### 18.2 I<sup>2</sup>C main features

- Parallel-bus/I<sup>2</sup>C protocol converter
- Multimaster capability: the same interface can act as Master or Slave
- I<sup>2</sup>C Master features:
  - Clock generation
  - Start and Stop generation
- I<sup>2</sup>C Slave features:
  - Programmable I<sup>2</sup>C Address detection
  - Dual Addressing Capability to acknowledge 2 slave addresses
  - Stop bit detection
- Generation and detection of 7-bit/10-bit addressing and General Call
- Supports different communication speeds:
  - Standard Speed (up to 100 kHz)
  - Fast Speed (up to 400 kHz)
  - The I<sup>2</sup>C bus frequency can be increased up to 1 MHz. For more details about the complete solution, please contact your local ST sales representative
- Analog noise filter
- Programmable digital noise filter
- Status flags:
  - Transmitter/Receiver mode flag
  - End-of-Byte transmission flag
  - I<sup>2</sup>C busy flag
- Error flags:
  - Arbitration lost condition for master mode
  - Acknowledgment failure after address/ data transmission
  - Detection of misplaced start or stop condition
  - Overrun/Underrun if clock stretching is disabled
- 2 Interrupt vectors:
  - 1 Interrupt for successful address/ data communication

- 1 Interrupt for error condition
- Optional clock stretching
- 1-byte buffer with DMA capability
- Configurable PEC (packet error checking) generation or verification:
  - PEC value can be transmitted as last byte in Tx mode
  - PEC error checking for last received byte
- SMBus 2.0 Compatibility:
  - 25 ms clock low timeout delay
  - 10 ms master cumulative clock low extend time
  - 25 ms slave cumulative clock low extend time
  - Hardware PEC generation/verification with ACK control
  - Address Resolution Protocol (ARP) supported
- PMBus Compatibility

*Note:* Some of the above features may not be available in certain products. The user should refer to the product data sheet, to identify the specific features supported by the I<sup>2</sup>C interface implementation.

## 18.3 I<sup>2</sup>C functional description

In addition to receiving and transmitting data, this interface converts it from serial to parallel format and vice versa. The interrupts are enabled or disabled by software. The interface is connected to the I<sup>2</sup>C bus by a data pin (SDA) and by a clock pin (SCL). It can be connected with a standard (up to 100 kHz) or fast (up to 400 kHz) I<sup>2</sup>C bus.

### 18.3.1 Mode selection

The interface can operate in one of the four following modes:

- Slave transmitter
- Slave receiver
- Master transmitter
- Master receiver

By default, it operates in slave mode. The interface automatically switches from slave to master, after it generates a START condition and from master to slave, if an arbitration loss or a Stop generation occurs, allowing multimaster capability.

#### Communication flow

In Master mode, the I<sup>2</sup>C interface initiates a data transfer and generates the clock signal. A serial data transfer always begins with a start condition and ends with a stop condition. Both start and stop conditions are generated in master mode by software.

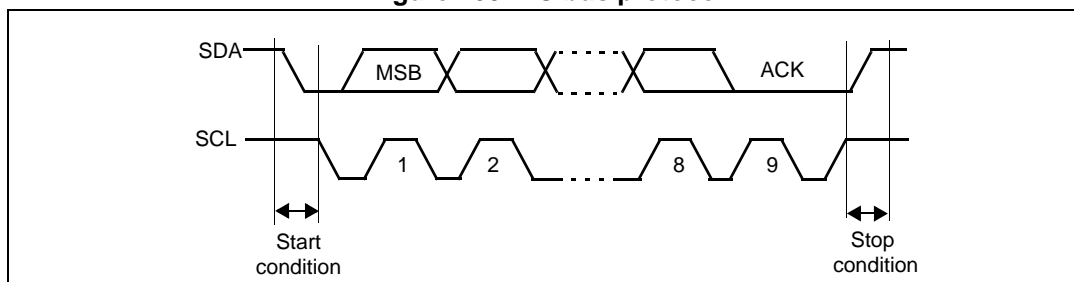
In Slave mode, the interface is capable of recognizing its own addresses (7 or 10-bit), and the General Call address. The General Call address detection may be enabled or disabled by software.

Data and addresses are transferred as 8-bit bytes, MSB first. The first byte(s) following the start condition contain the address (one in 7-bit mode, two in 10-bit mode). The address is always transmitted in Master mode.



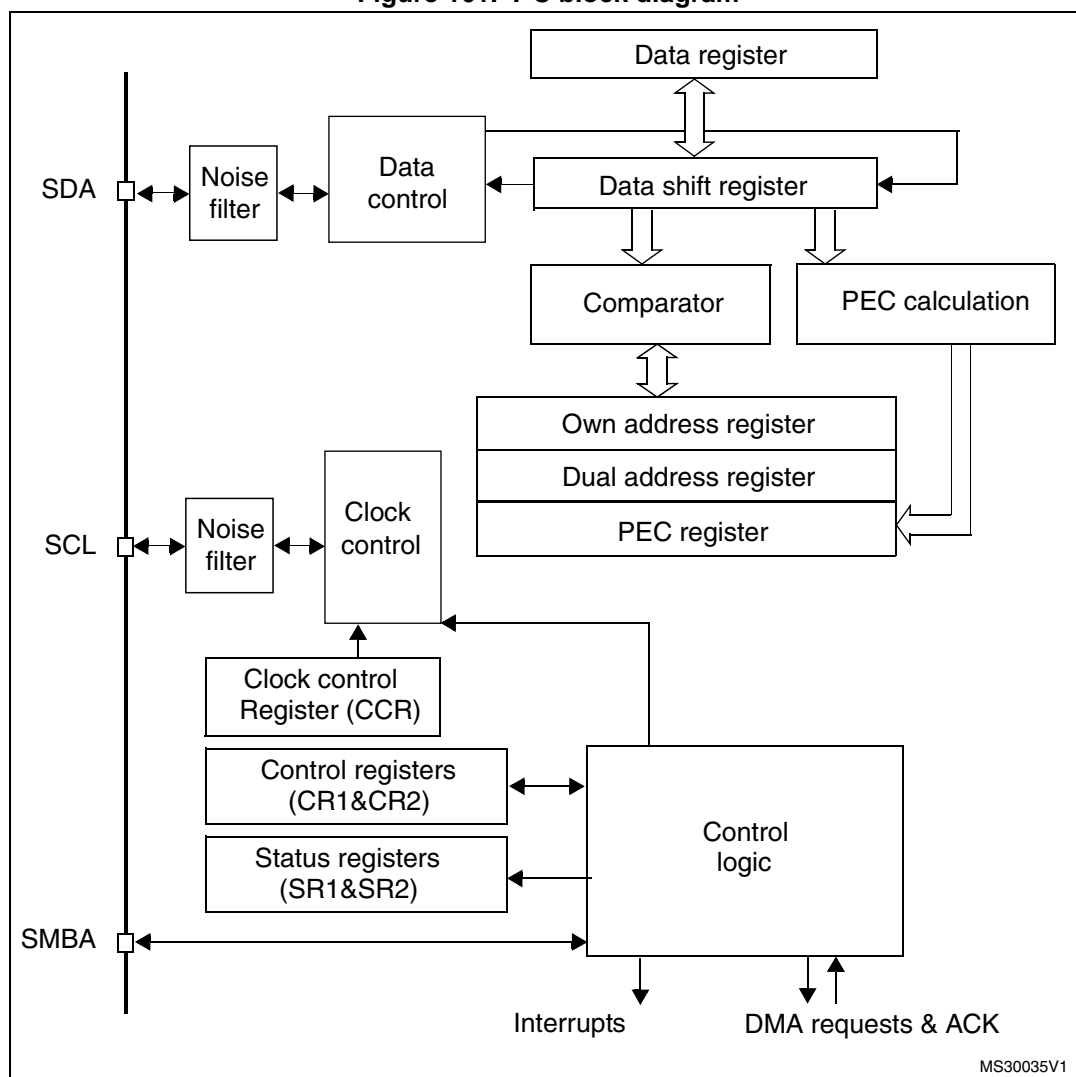
A 9th clock pulse follows the 8 clock cycles of a byte transfer, during which the receiver must send an acknowledge bit to the transmitter. Refer to [Figure 160](#).

**Figure 160. I<sup>2</sup>C bus protocol**



Acknowledge may be enabled or disabled by software. The I<sup>2</sup>C interface addresses (dual addressing 7-bit/ 10-bit and/or general call address) can be selected by software.

The block diagram of the I<sup>2</sup>C interface is shown in [Figure 161](#).

Figure 161. I<sup>2</sup>C block diagram

1. SMBA is an optional signal in SMBus mode. This signal is not applicable if SMBus is disabled.

### 18.3.2 I<sup>2</sup>C slave mode

By default the I<sup>2</sup>C interface operates in Slave mode. To switch from default Slave mode to Master mode a Start condition generation is needed.

The peripheral input clock must be programmed in the I2C\_CR2 register in order to generate correct timings. The peripheral input clock frequency must be at least:

- 2 MHz in Sm mode
- 4 MHz in Fm mode

As soon as a start condition is detected, the address is received from the SDA line and sent to the shift register. Then it is compared with the address of the interface (OAR1) and with OAR2 (if ENDUAL=1) or the General Call address (if ENGC = 1).

*Note:* In 10-bit addressing mode, the comparison includes the header sequence (11110xx0), where xx denotes the two most significant bits of the address.

**Header or address not matched:** the interface ignores it and waits for another Start condition.

**Header matched** (10-bit mode only): the interface generates an acknowledge pulse if the ACK bit is set and waits for the 8-bit slave address.

**Address matched:** the interface generates in sequence:

- An acknowledge pulse if the ACK bit is set
- The ADDR bit is set by hardware and an interrupt is generated if the ITEVFEN bit is set.
- If ENDUAL=1, the software has to read the DUALF bit to check which slave address has been acknowledged.

In 10-bit mode, after receiving the address sequence the slave is always in Receiver mode. It will enter Transmitter mode on receiving a repeated Start condition followed by the header sequence with matching address bits and the least significant bit set (11110xx1).

The TRA bit indicates whether the slave is in Receiver or Transmitter mode.

### Slave transmitter

Following the address reception and after clearing ADDR, the slave sends bytes from the DR register to the SDA line via the internal shift register.

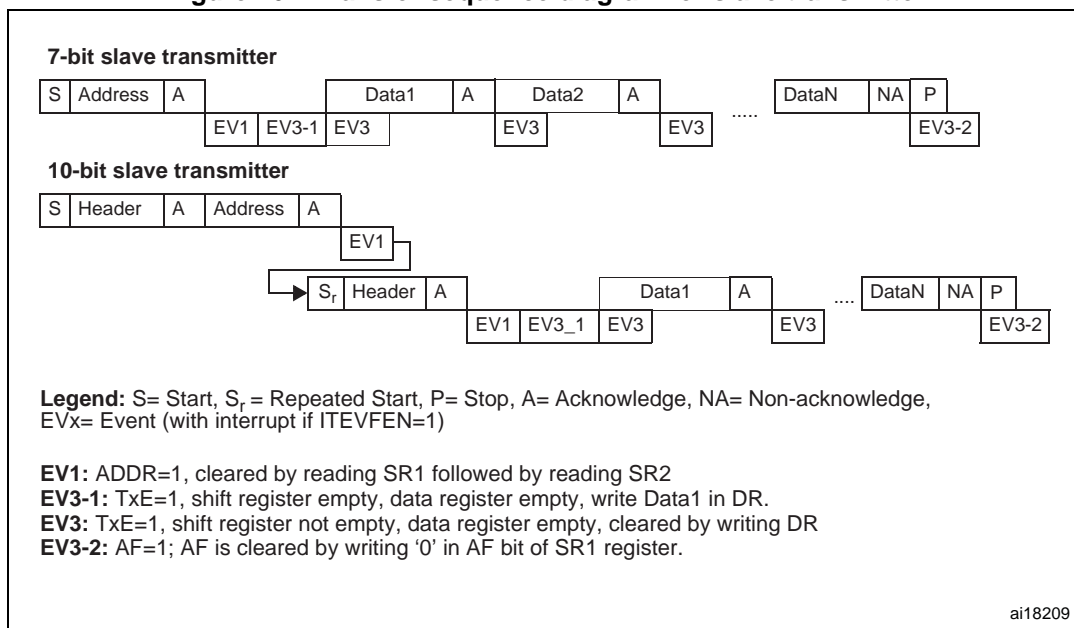
The slave stretches SCL low until ADDR is cleared and DR filled with the data to be sent (see [Figure 162](#) Transfer sequencing EV1 EV3).

When the acknowledge pulse is received:

- The TxE bit is set by hardware with an interrupt if the ITEVFEN and the ITBUFEN bits are set.

If TxE is set and some data were not written in the I2C\_DR register before the end of the next data transmission, the BTF bit is set and the interface waits until BTF is cleared by a read to I2C\_SR1 followed by a write to the I2C\_DR register, stretching SCL low.

Figure 162. Transfer sequence diagram for slave transmitter



1. The EV1 and EV3\_1 events stretch SCL low until the end of the corresponding software sequence.
2. The EV3 event stretches SCL low if the software sequence is not completed before the end of the next byte transmission

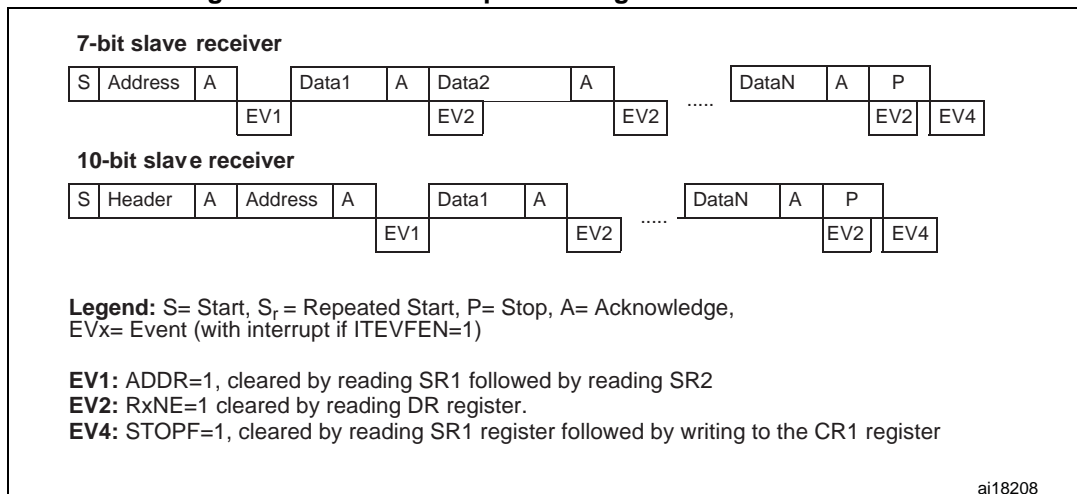
**Slave receiver**

Following the address reception and after clearing ADDR, the slave receives bytes from the SDA line into the DR register via the internal shift register. After each byte the interface generates in sequence:

- An acknowledge pulse if the ACK bit is set
- The RxNE bit is set by hardware and an interrupt is generated if the ITEVFEN and ITBUFEN bit is set.

If RxNE is set and the data in the DR register is not read before the end of the next data reception, the BTF bit is set and the interface waits until BTF is cleared by a read from the I2C\_DR register, stretching SCL low (see [Figure 163](#) Transfer sequencing).

Figure 163. Transfer sequence diagram for slave receiver



1. The EV1 event stretches SCL low until the end of the corresponding software sequence.
2. The EV2 event stretches SCL low if the software sequence is not completed before the end of the next byte reception.
3. After checking the SR1 register content, the user should perform the complete clearing sequence for each flag found set.  
 Thus, for ADDR and STOPF flags, the following sequence is required inside the I2C interrupt routine:  
 READ SR1  
 if (ADDR == 1) {READ SR1; READ SR2}  
 if (STOPF == 1) {READ SR1; WRITE CR1}  
 The purpose is to make sure that both ADDR and STOPF flags are cleared if both are found set.

### Closing slave communication

After the last data byte is transferred a Stop Condition is generated by the master. The interface detects this condition and sets:

- The STOPF bit and generates an interrupt if the ITEVFEN bit is set.

The STOPF bit is cleared by a read of the SR1 register followed by a write to the CR1 register (see [Figure 163: Transfer sequence diagram for slave receiver](#) EV4).

### 18.3.3 I<sup>2</sup>C master mode

In Master mode, the I<sup>2</sup>C interface initiates a data transfer and generates the clock signal. A serial data transfer always begins with a Start condition and ends with a Stop condition. Master mode is selected as soon as the Start condition is generated on the bus with a START bit.

The following is the required sequence in master mode.

- Program the peripheral input clock in I2C\_CR2 Register in order to generate correct timings
- Configure the clock control registers
- Configure the rise time register
- Program the I2C\_CR1 register to enable the peripheral
- Set the START bit in the I2C\_CR1 register to generate a Start condition

The peripheral input clock frequency must be at least:

- 2 MHz in Sm mode
- 4 MHz in Fm mode

### SCL master clock generation

The CCR bits are used to generate the high and low level of the SCL clock, starting from the generation of the rising and falling edge (respectively). As a slave may stretch the SCL line, the peripheral checks the SCL input from the bus at the end of the time programmed in TRISE bits after rising edge generation.

- If the SCL line is low, it means that a slave is stretching the bus, and the high level counter stops until the SCL line is detected high. This allows to guarantee the minimum HIGH period of the SCL clock parameter.
- If the SCL line is high, the high level counter keeps on counting.

Indeed, the feedback loop from the SCL rising edge generation by the peripheral to the SCL rising edge detection by the peripheral takes time even if no slave stretches the clock. This loopback duration is linked to the SCL rising time (impacting SCL VIH input detection), plus delay due to the noise filter present on the SCL input path, plus delay due to internal SCL input synchronization with APB clock. The maximum time used by the feedback loop is programmed in the TRISE bits, so that the SCL frequency remains stable whatever the SCL rising time.

### Start condition

Setting the START bit causes the interface to generate a Start condition and to switch to Master mode (MSL bit set) when the BUSY bit is cleared.

*Note:* In master mode, setting the START bit causes the interface to generate a ReStart condition at the end of the current byte transfer.

Once the Start condition is sent:

- The SB bit is set by hardware and an interrupt is generated if the ITEVFEN bit is set.

Then the master waits for a read of the SR1 register followed by a write in the DR register with the Slave address (see [Figure 164](#) and [Figure 165](#) Transfer sequencing EV5).

### Slave address transmission

Then the slave address is sent to the SDA line via the internal shift register.

- In 10-bit addressing mode, sending the header sequence causes the following event:
  - The ADD10 bit is set by hardware and an interrupt is generated if the ITEVFEN bit is set.

Then the master waits for a read of the SR1 register followed by a write in the DR register with the second address byte (see [Figure 164](#) and [Figure 165](#) Transfer sequencing).

- The ADDR bit is set by hardware and an interrupt is generated if the ITEVFEN bit is set.

Then the master waits for a read of the SR1 register followed by a read of the SR2 register (see [Figure 164](#) and [Figure 165](#) Transfer sequencing).

- In 7-bit addressing mode, one address byte is sent.

As soon as the address byte is sent,

- The ADDR bit is set by hardware and an interrupt is generated if the ITEVFEN bit is set.

Then the master waits for a read of the SR1 register followed by a read of the SR2 register (see [Figure 164](#) and [Figure 165](#) Transfer sequencing).

The master can decide to enter Transmitter or Receiver mode depending on the LSB of the slave address sent.

- In 7-bit addressing mode,
  - To enter Transmitter mode, a master sends the slave address with LSB reset.
  - To enter Receiver mode, a master sends the slave address with LSB set.
- In 10-bit addressing mode,
  - To enter Transmitter mode, a master sends the header (11110xx0) and then the slave address, (where xx denotes the two most significant bits of the address).
  - To enter Receiver mode, a master sends the header (11110xx0) and then the slave address. Then it should send a repeated Start condition followed by the header (11110xx1), (where xx denotes the two most significant bits of the address).

The TRA bit indicates whether the master is in Receiver or Transmitter mode.

### Master transmitter

Following the address transmission and after clearing ADDR, the master sends bytes from the DR register to the SDA line via the internal shift register.

The master waits until the first data byte is written into I2C\_DR (see [Figure 164](#) Transfer sequencing EV8\_1).

When the acknowledge pulse is received, the TxE bit is set by hardware and an interrupt is generated if the ITEVFEN and ITBUFEN bits are set.

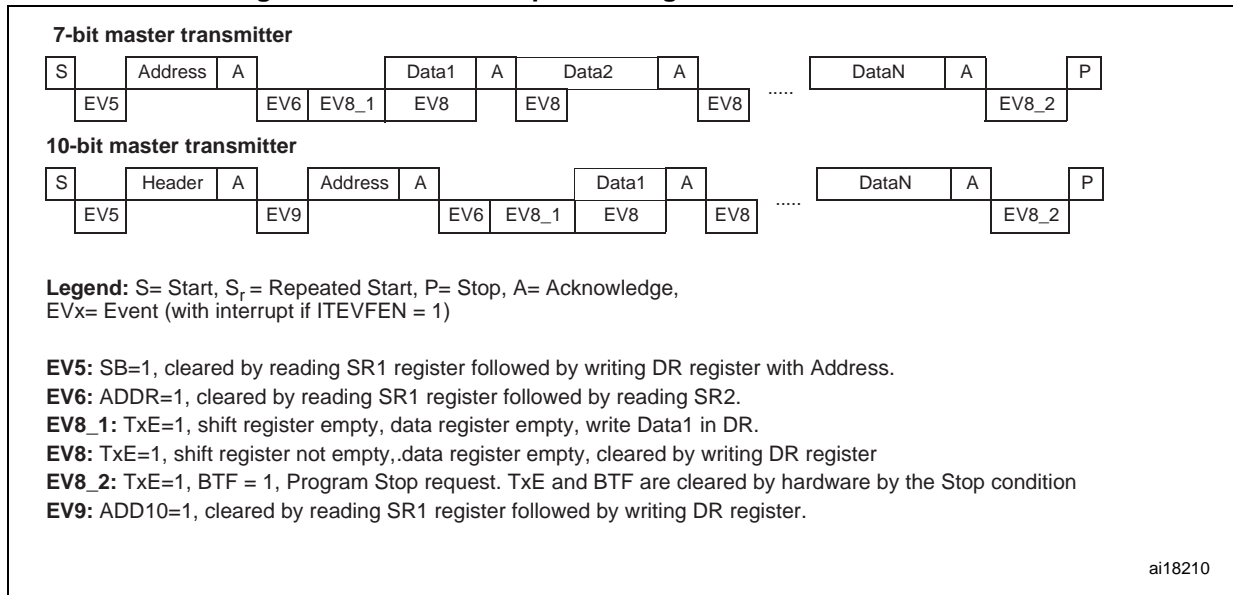
If TxE is set and a data byte was not written in the DR register before the end of the last data transmission, BTF is set and the interface waits until BTF is cleared by a write to I2C\_DR, stretching SCL low.

### Closing the communication

After the last byte is written to the DR register, the STOP bit is set by software to generate a Stop condition (see [Figure 164](#) Transfer sequencing EV8\_2). The interface automatically goes back to slave mode (MSL bit cleared).

*Note:* Stop condition should be programmed during EV8\_2 event, when either TxE or BTF is set.

Figure 164. Transfer sequence diagram for master transmitter



1. The EV5, EV6, EV9, EV8\_1 and EV8\_2 events stretch SCL low until the end of the corresponding software sequence.
2. The EV8 event stretches SCL low if the software sequence is not complete before the end of the next byte transmission.



### Master receiver

Following the address transmission and after clearing ADDR, the I<sup>2</sup>C interface enters Master Receiver mode. In this mode the interface receives bytes from the SDA line into the DR register via the internal shift register. After each byte the interface generates in sequence:

1. An acknowledge pulse if the ACK bit is set
2. The RxNE bit is set and an interrupt is generated if the ITEVFEN and ITBUFEN bits are set (see [Figure 165](#) Transfer sequencing EV7).

If the RxNE bit is set and the data in the DR register is not read before the end of the last data reception, the BTF bit is set by hardware and the interface waits until BTF is cleared by a read in the DR register, stretching SCL low.

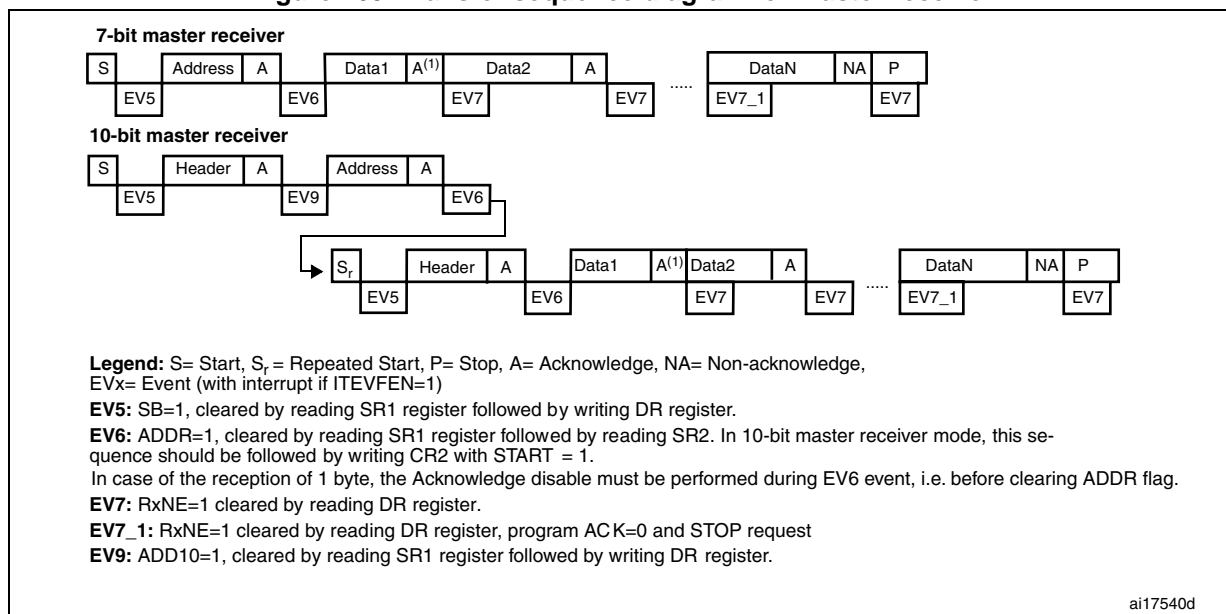
### Closing the communication

The master sends a NACK for the last byte received from the slave. After receiving this NACK, the slave releases the control of the SCL and SDA lines. Then the master can send a Stop/Restart condition.

1. To generate the nonacknowledge pulse after the last received data byte, the ACK bit must be cleared just after reading the second last data byte (after second last RxNE event).
2. In order to generate the Stop/Restart condition, software must set the STOP/START bit after reading the second last data byte (after the second last RxNE event).
3. In case a single byte has to be received, the Acknowledge disable is made during EV6 (before ADDR flag is cleared) and the STOP condition generation is made after EV6.

After the Stop condition generation, the interface goes automatically back to slave mode (MSL bit cleared).

Figure 165. Transfer sequence diagram for master receiver



1. If a single byte is received, it is NA.
2. The EV5, EV6 and EV9 events stretch SCL low until the end of the corresponding software sequence.
3. The EV7 event stretches SCL low if the software sequence is not completed before the end of the next byte reception.
4. The EV7\_1 software sequence must be completed before the ACK pulse of the current byte transfer.

The procedures described below are recommended if the EV7-1 software sequence is not completed before the ACK pulse of the current byte transfer.

These procedures must be followed to make sure:

- The ACK bit is set low on time before the end of the last data reception
- The STOP bit is set high after the last data reception without reception of supplementary data.

**For 2-byte reception:**

- Wait until ADDR = 1 (SCL stretched low until the ADDR flag is cleared)
- Set ACK low, set POS high
- Clear ADDR flag
- Wait until BTF = 1 (Data 1 in DR, Data2 in shift register, SCL stretched low until a data 1 is read)
- Set STOP high
- Read data 1 and 2

**For N > 2 -byte reception, from N-2 data reception**

- Wait until BTF = 1 (data N-2 in DR, data N-1 in shift register, SCL stretched low until data N-2 is read)
- Set ACK low
- Read data N-2
- Wait until BTF = 1 (data N-1 in DR, data N in shift register, SCL stretched low until a data N-1 is read)
- Set STOP high
- Read data N-1 and N

**18.3.4 Error conditions**

The following are the error conditions which may cause communication to fail.

**Bus error (BERR)**

This error occurs when the I<sup>2</sup>C interface detects an external Stop or Start condition during an address or a data transfer. In this case:

- the BERR bit is set and an interrupt is generated if the ITERREN bit is set
- in Slave mode: data are discarded and the lines are released by hardware:
  - in case of a misplaced Start, the slave considers it is a restart and waits for an address, or a Stop condition
  - in case of a misplaced Stop, the slave behaves like for a Stop condition and the lines are released by hardware
- In Master mode: the lines are not released and the state of the current transmission is not affected. It is up to the software to abort or not the current transmission

**Acknowledge failure (AF)**

This error occurs when the interface detects a nonacknowledge bit. In this case:

- the AF bit is set and an interrupt is generated if the ITERREN bit is set
- a transmitter which receives a NACK must reset the communication:
  - If Slave: lines are released by hardware
  - If Master: a Stop or repeated Start condition must be generated by software

**Arbitration lost (ARLO)**

This error occurs when the I<sup>2</sup>C interface detects an arbitration lost condition. In this case,

- the ARLO bit is set by hardware (and an interrupt is generated if the ITERREN bit is set)
- the I<sup>2</sup>C Interface goes automatically back to slave mode (the MSL bit is cleared). When the I<sup>2</sup>C loses the arbitration, it is not able to acknowledge its slave address in the same transfer, but it can acknowledge it after a repeated Start from the winning master.
- lines are released by hardware

### Overrun/underrun error (OVR)

An overrun error can occur in slave mode when clock stretching is disabled and the I<sup>2</sup>C interface is receiving data. The interface has received a byte (RxNE=1) and the data in DR has not been read, before the next byte is received by the interface. In this case,

- The last received byte is lost.
- In case of Overrun error, software should clear the RxNE bit and the transmitter should re-transmit the last received byte.

Underrun error can occur in slave mode when clock stretching is disabled and the I<sup>2</sup>C interface is transmitting data. The interface has not updated the DR with the next byte (TxE=1), before the clock comes for the next byte. In this case,

- The same byte in the DR register will be sent again
- The user should make sure that data received on the receiver side during an underrun error are discarded and that the next bytes are written within the clock low time specified in the I<sup>2</sup>C bus standard.

For the first byte to be transmitted, the DR must be written after ADDR is cleared and before the first SCL rising edge. If not possible, the receiver must discard the first data.

### 18.3.5 Programmable noise filter

In Fm mode, the I<sup>2</sup>C standard requires that spikes are suppressed to a length of 50 ns on SDA and SCL lines.

An analog noise filter is implemented in the SDA and SCL I/Os. This filter is enabled by default and can be disabled by setting the ANOFF bit in the I2C\_FLTR register.

A digital noise filter can be enabled by configuring the DNF[3:0] bits to a non-zero value. This suppresses the spikes on SDA and SCL inputs with a length of up to  $DNF[3:0] * T_{PCLK1}$ .

Enabling the digital noise filter increases the SDA hold time by  $(DNF[3:0] + 1) * T_{PCLK1}$ .

To be compliant with the maximum hold time of the I<sup>2</sup>C-bus specification version 2.1 (Thd:dat), the DNF bits must be programmed using the constraints shown in [Table 69](#), and assuming that the analog filter is disabled.

*Note: DNF[3:0] must only be configured when the I<sup>2</sup>C is disabled (PE = 0). If the analog filter is also enabled, the digital filter is added to the analog filter.*

**Table 69. Maximum DNF[3:0] value to be compliant with Thd:dat(max)**

PCLK1 frequency	Maximum DNF value	
	Sm mode	Fm mode
$2 \leq F_{PCLK1} \leq 5$	2	0
$5 < F_{PCLK1} \leq 10$	12	0
$10 < F_{PCLK1} \leq 20$	15	1
$20 < F_{PCLK1} \leq 30$	15	7
$30 < F_{PCLK1} \leq 40$	15	13
$40 < F_{PCLK1} \leq 50$	15	15

*Note:* For each frequency range, the constraint is given based on the worst case which is the minimum frequency of the range. Greater DNF values can be used if the system can support maximum hold time violation.

### 18.3.6 SDA/SCL line control

- If clock stretching is enabled:
  - Transmitter mode: If TxNE=1 and BTF=1: the interface holds the clock line low before transmission to wait for the microcontroller to write the byte in the Data Register (both buffer and shift register are empty).
  - Receiver mode: If RxNE=1 and BTF=1: the interface holds the clock line low after reception to wait for the microcontroller to read the byte in the Data Register (both buffer and shift register are full).
- If clock stretching is disabled in Slave mode:
  - Overrun Error in case of RxNE=1 and no read of DR has been done before the next byte is received. The last received byte is lost.
  - Underrun Error in case TxNE=1 and no write into DR has been done before the next byte must be transmitted. The same byte will be sent again.
  - Write Collision not managed.

### 18.3.7 SMBus

#### Introduction

The System Management Bus (SMBus) is a two-wire interface through which various devices can communicate with each other and with the rest of the system. It is based on I<sup>2</sup>C principles of operation. SMBus provides a control bus for system and power management related tasks. A system may use SMBus to pass messages to and from devices instead of toggling individual control lines.

The System Management Bus Specification refers to three types of devices. A *slave* is a device that is receiving or responding to a command. A *master* is a device that issues commands, generates the clocks, and terminates the transfer. A *host* is a specialized master that provides the main interface to the system's CPU. A host must be a master-slave and must support the SMBus host notify protocol. Only one host is allowed in a system.

#### Similarities between SMBus and I<sup>2</sup>C

- 2 wire bus protocol (1 Clk, 1 Data) + SMBus Alert line optional
- Master-slave communication, Master provides clock
- Multi master capability
- SMBus data format similar to I<sup>2</sup>C 7-bit addressing format ([Figure 160](#)).

#### Differences between SMBus and I<sup>2</sup>C

The following table describes the differences between SMBus and I<sup>2</sup>C.

Table 70. SMBus vs. I<sup>2</sup>C

SMBus	I <sup>2</sup> C
Max. speed 100 kHz	Max. speed 400 kHz
Min. clock speed 10 kHz	No minimum clock speed
35 ms clock low timeout	No timeout
Logic levels are fixed	Logic levels are V <sub>DD</sub> dependent
Different address types (reserved, dynamic etc.)	7-bit, 10-bit and general call slave address types
Different bus protocols (quick command, process call etc.)	No bus protocols

### SMBus application usage

With System Management Bus, a device can provide manufacturer information, tell the system what its model/part number is, save its state for a suspend event, report different types of errors, accept control parameters, and return its status. SMBus provides a control bus for system and power management related tasks.

### Device identification

Any device that exists on the System Management Bus as a slave has a unique address called the Slave Address. For the list of reserved slave addresses, refer to the SMBus specification version. 2.0 (<http://smbus.org>).

### Bus protocols

The SMBus specification supports up to 9 bus protocols. For more details of these protocols and SMBus address types, refer to SMBus specification version. 2.0 (<http://smbus.org>). These protocols should be implemented by the user software.

### Address resolution protocol (ARP)

SMBus slave address conflicts can be resolved by dynamically assigning a new unique address to each slave device. The Address Resolution Protocol (ARP) has the following attributes:

- Address assignment uses the standard SMBus physical layer arbitration mechanism
- Assigned addresses remain constant while device power is applied; address retention through device power loss is also allowed
- No additional SMBus packet overhead is incurred after address assignment. (i.e. subsequent accesses to assigned slave addresses have the same overhead as accesses to fixed address devices.)
- Any SMBus master can enumerate the bus

### Unique device identifier (UDID)

In order to provide a mechanism to isolate each device for the purpose of address assignment, each device must implement a unique device identifier (UDID).

For the details on 128 bit UDID and more information on ARP, refer to SMBus specification version 2.0 (<http://smbus.org>).

### SMBus alert mode

SMBus Alert is an optional signal with an interrupt line for devices that want to trade their ability to master for a pin. SMBA is a wired-AND signal just as the SCL and SDA signals are. SMBA is used in conjunction with the SMBus General Call Address. Messages invoked with the SMBus are 2 bytes long.

A slave-only device can signal the host through SMBA that it wants to talk by setting ALERT bit in I2C\_CR1 register. The host processes the interrupt and simultaneously accesses all SMBA devices through the *Alert Response Address* (known as ARA having a value 0001 100X). Only the device(s) which pulled SMBA low will acknowledge the Alert Response Address. This status is identified using SMBALERT Status flag in I2C\_SR1 register. The host performs a modified Receive Byte operation. The 7 bit device address provided by the slave transmit device is placed in the 7 most significant bits of the byte. The eighth bit can be a zero or one.

If more than one device pulls SMBA low, the highest priority (lowest address) device will win communication rights via standard arbitration during the slave address transfer. After acknowledging the slave address the device must disengage its SMBA pull-down. If the host still sees SMBA low when the message transfer is complete, it knows to read the ARA again.

A host which does not implement the SMBA signal may periodically access the ARA.

For more details on SMBus Alert mode, refer to SMBus specification version 2.0 (<http://smbus.org>).

### Timeout error

There are differences in the timing specifications between I<sup>2</sup>C and SMBus. SMBus defines a clock low timeout, TIMEOUT of 35 ms. Also SMBus specifies TLOW: SEXT as the cumulative clock low extend time for a slave device. SMBus specifies TLOW: MEXT as the cumulative clock low extend time for a master device. For more details on these timeouts, refer to SMBus specification version 2.0 (<http://smbus.org>).

The status flag Timeout or Tlow Error in I2C\_SR1 shows the status of this feature.

### How to use the interface in SMBus mode

To switch from I<sup>2</sup>C mode to SMBus mode, the following sequence should be performed.

- Set the SMBus bit in the I2C\_CR1 register
- Configure the SMBTYPE and ENARP bits in the I2C\_CR1 register as required for the application

If you want to configure the device as a master, follow the Start condition generation procedure in [Section 18.3.3: I2C master mode](#). Otherwise, follow the sequence in [Section 18.3.2: I2C slave mode](#).

The application has to control the various SMBus protocols by software.

- SMB Device Default Address acknowledged if ENARP=1 and SMBTYPE=0
- SMB Host Header acknowledged if ENARP=1 and SMBTYPE=1
- SMB Alert Response Address acknowledged if SMBALERT=1

### 18.3.8 DMA requests

DMA requests (when enabled) are generated only for data transfer. DMA requests are generated by Data Register becoming empty in transmission and Data Register becoming full in reception. The DMA must be initialized and enabled before the I2C data transfer. The DMAEN bit must be set in the I2C\_CR2 register before the ADDR event. In master mode or in slave mode when clock stretching is enabled, the DMAEN bit can also be set during the ADDR event, before clearing the ADDR flag. The DMA request must be served before the end of the current byte transfer. When the number of data transfers which has been programmed for the corresponding DMA stream is reached, the DMA controller sends an End of Transfer EOT signal to the I<sup>2</sup>C interface and generates a Transfer Complete interrupt if enabled:

- Master transmitter: In the interrupt routine after the EOT interrupt, disable DMA requests then wait for a BTF event before programming the Stop condition.
- Master receiver
  - When the number of bytes to be received is equal to or greater than two, the DMA controller sends a hardware signal, EOT\_1, corresponding to the last but one data byte (number\_of\_bytes – 1). If, in the I2C\_CR2 register, the LAST bit is set, I<sup>2</sup>C automatically sends a NACK after the next byte following EOT\_1. The user can generate a Stop condition in the DMA Transfer Complete interrupt routine if enabled.
  - When a single byte must be received: the NACK must be programmed during EV6 event, i.e. program ACK=0 when ADDR=1, before clearing ADDR flag. Then the user can program the STOP condition either after clearing ADDR flag, or in the DMA Transfer Complete interrupt routine.

#### Transmission using DMA

DMA mode can be enabled for transmission by setting the DMAEN bit in the I2C\_CR2 register. Data will be loaded from a Memory area configured using the DMA peripheral (refer to the DMA specification) to the I2C\_DR register whenever the TxE bit is set. To map a DMA stream x for I<sup>2</sup>C transmission (where x is the stream number), perform the following sequence:

1. Set the I2C\_DR register address in the DMA\_SxPAR register. The data will be moved to this address from the memory after each TxE event.
2. Set the memory address in the DMA\_SxMA0R register (and in DMA\_SxMA1R register in the case of a double buffer mode). The data will be loaded into I2C\_DR from this memory after each TxE event.
3. Configure the total number of bytes to be transferred in the DMA\_SxNDTR register. After each TxE event, this value will be decremented.
4. Configure the DMA stream priority using the PL[0:1] bits in the DMA\_SxCR register
5. Set the DIR bit in the DMA\_SxCR register and configure interrupts after half transfer or full transfer depending on application requirements.
6. Activate the stream by setting the EN bit in the DMA\_SxCR register.

When the number of data transfers which has been programmed in the DMA Controller registers is reached, the DMA controller sends an End of Transfer EOT/ EOT\_1 signal to the I<sup>2</sup>C interface and the DMA generates an interrupt, if enabled, on the DMA stream interrupt vector.

*Note:* Do not enable the ITBUFEN bit in the I2C\_CR2 register if DMA is used for transmission.



### Reception using DMA

DMA mode can be enabled for reception by setting the DMAEN bit in the I2C\_CR2 register. Data will be loaded from the I2C\_DR register to a Memory area configured using the DMA peripheral (refer to the DMA specification) whenever a data byte is received. To map a DMA stream x for I<sup>2</sup>C reception (where x is the stream number), perform the following sequence:

1. Set the I2C\_DR register address in DMA\_SxPAR register. The data will be moved from this address to the memory after each RxNE event.
2. Set the memory address in the DMA\_SxMA0R register (and in DMA\_SxMA1R register in the case of a double buffer mode). The data will be loaded from the I2C\_DR register to this memory area after each RxNE event.
3. Configure the total number of bytes to be transferred in the DMA\_SxNDTR register. After each RxNE event, this value will be decremented.
4. Configure the stream priority using the PL[0:1] bits in the DMA\_SxCR register
5. Reset the DIR bit and configure interrupts in the DMA\_SxCR register after half transfer or full transfer depending on application requirements.
6. Activate the stream by setting the EN bit in the DMA\_SxCR register.

When the number of data transfers which has been programmed in the DMA Controller registers is reached, the DMA controller sends an End of Transfer EOT/ EOT\_1 signal to the I<sup>2</sup>C interface and DMA generates an interrupt, if enabled, on the DMA stream interrupt vector.

*Note:* Do not enable the ITBUFEN bit in the I2C\_CR2 register if DMA is used for reception.

### 18.3.9 Packet error checking

A PEC calculator has been implemented to improve the reliability of communication. The PEC is calculated by using the  $C(x) = x^8 + x^2 + x + 1$  CRC-8 polynomial serially on each bit.

- PEC calculation is enabled by setting the ENPEC bit in the I2C\_CR1 register. PEC is a CRC-8 calculated on all message bytes including addresses and R/W bits.
  - In transmission: set the PEC transfer bit in the I2C\_CR1 register after the TxE event corresponding to the last byte. The PEC will be transferred after the last transmitted byte.
  - In reception: set the PEC bit in the I2C\_CR1 register after the RxNE event corresponding to the last byte so that the receiver sends a NACK if the next received byte is not equal to the internally calculated PEC. In case of Master-Receiver, a NACK must follow the PEC whatever the check result. The PEC must

be set before the ACK of the CRC reception in slave mode. It must be set when the ACK is set low in master mode.

- A PECERR error flag/interrupt is also available in the I2C\_SR1 register.
- If DMA and PEC calculation are both enabled:-
  - In transmission: when the I<sup>2</sup>C interface receives an EOT signal from the DMA controller, it automatically sends a PEC after the last byte.
  - In reception: when the I<sup>2</sup>C interface receives an EOT\_1 signal from the DMA controller, it will automatically consider the next byte as a PEC and will check it. A DMA request is generated after PEC reception.
- To allow intermediate PEC transfers, a control bit is available in the I2C\_CR2 register (LAST bit) to determine if it is really the last DMA transfer or not. If it is the last DMA request for a master receiver, a NACK is automatically sent after the last received byte.
- PEC calculation is corrupted by an arbitration loss.

## 18.4 I<sup>2</sup>C interrupts

The table below gives the list of I<sup>2</sup>C interrupt requests.

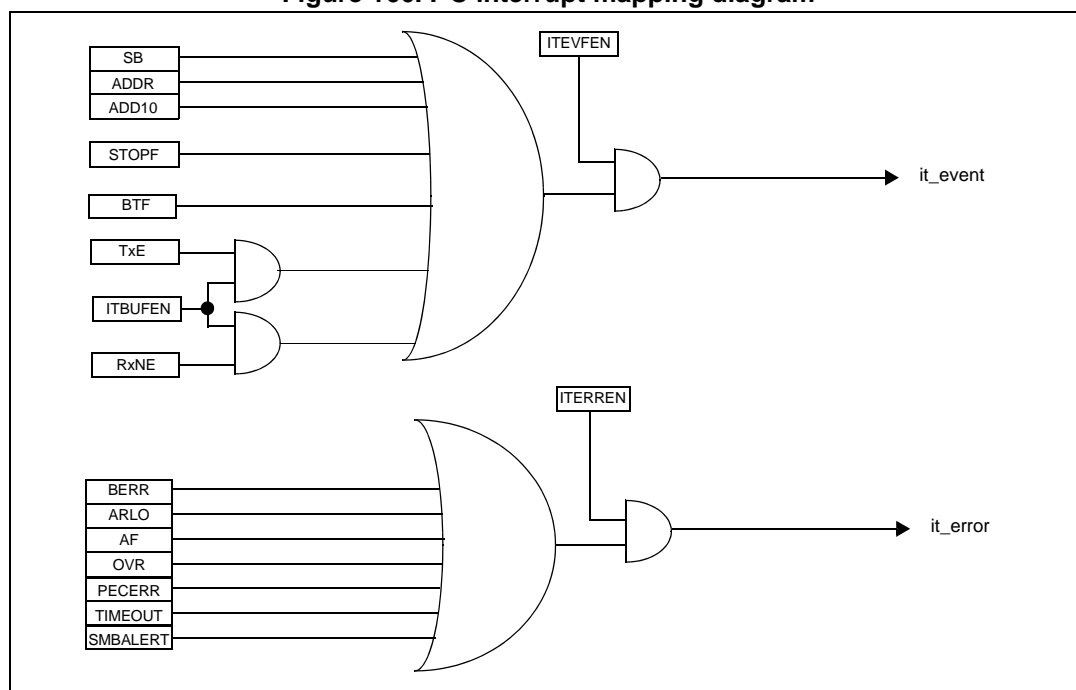
**Table 71. I<sup>2</sup>C Interrupt requests**

Interrupt event	Event flag	Enable control bit
Start bit sent (Master)	SB	ITEVFEN
Address sent (Master) or Address matched (Slave)	ADDR	
10-bit header sent (Master)	ADD10	
Stop received (Slave)	STOPF	
Data byte transfer finished	BTF	
Receive buffer not empty	RxNE	ITEVFEN and ITBUFEN
Transmit buffer empty	TxE	
Bus error	BERR	ITERREN
Arbitration loss (Master)	ARLO	
Acknowledge failure	AF	
Overrun/Underrun	OVR	
PEC error	PECERR	
Timeout/Tlow error	TIMEOUT	
SMBus Alert	SMBALERT	

*Note:* SB, ADDR, ADD10, STOPF, BTF, RxNE and TxE are logically ORed on the same interrupt channel.

*BERR, ARLO, AF, OVR, PECERR, TIMEOUT and SMBALERT are logically ORed on the same interrupt channel.*

Figure 166. I<sup>2</sup>C interrupt mapping diagram



## 18.5 I<sup>2</sup>C debug mode

When the microcontroller enters the debug mode (Cortex<sup>®</sup>-M4 with FPU core halted), the SMBUS timeout either continues to work normally or stops, depending on the DBG\_I2Cx\_SMBUS\_TIMEOUT configuration bits in the DBG module. For more details, refer to [Section 23.16.2: Debug support for timers, watchdog and I2C on page 820](#).

## 18.6 I<sup>2</sup>C registers

Refer to [Section 1.1 on page 34](#) for a list of abbreviations used in register descriptions.

The peripheral registers have to be accessed by half-words (16 bits) or words (32 bits).

### 18.6.1 I<sup>2</sup>C Control register 1 (I2C\_CR1)

Address offset: 0x00

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
SWRST	Res.	ALERT	PEC	POS	ACK	STOP	START	NO STRETCH	ENGC	ENPEC	ENARP	SMB TYPE	Res.	SMBUS	PE
rw		rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw		rw	rw

Bit 15 **SWRST**: Software reset

When set, the I2C is under reset state. Before resetting this bit, make sure the I2C lines are released and the bus is free.

0: I<sup>2</sup>C Peripheral not under reset

1: I<sup>2</sup>C Peripheral under reset state

*Note: This bit can be used to reinitialize the peripheral after an error or a locked state. As an example, if the BUSY bit is set and remains locked due to a glitch on the bus, the SWRST bit can be used to exit from this state.*

Bit 14 Reserved, must be kept at reset value

Bit 13 **ALERT**: SMBus alert

This bit is set and cleared by software, and cleared by hardware when PE=0.

0: Releases SMBA pin high. Alert Response Address Header followed by NACK.

1: Drives SMBA pin low. Alert Response Address Header followed by ACK.

Bit 12 **PEC**: Packet error checking

This bit is set and cleared by software, and cleared by hardware when PEC is transferred or by a START or Stop condition or when PE=0.

0: No PEC transfer

1: PEC transfer (in Tx or Rx mode)

*Note: PEC calculation is corrupted by an arbitration loss.*

Bit 11 **POS**: Acknowledge/PEC Position (for data reception)

This bit is set and cleared by software and cleared by hardware when PE=0.

0: ACK bit controls the (N)ACK of the current byte being received in the shift register. The PEC bit indicates that current byte in shift register is a PEC.

1: ACK bit controls the (N)ACK of the next byte which will be received in the shift register. The PEC bit indicates that the next byte in the shift register is a PEC

*Note: The POS bit must be used only in 2-byte reception configuration in master mode. It must be configured before data reception starts, as described in the 2-byte reception procedure recommended in [Section : Master receiver on page 476](#).*

- Bit 10 **ACK**: Acknowledge enable  
This bit is set and cleared by software and cleared by hardware when PE=0.  
0: No acknowledge returned  
1: Acknowledge returned after a byte is received (matched address or data)
- Bit 9 **STOP**: Stop generation  
The bit is set and cleared by software, cleared by hardware when a Stop condition is detected, set by hardware when a timeout error is detected.  
In Master Mode:  
0: No Stop generation.  
1: Stop generation after the current byte transfer or after the current Start condition is sent.  
In Slave mode:  
0: No Stop generation.  
1: Release the SCL and SDA lines after the current byte transfer.
- Bit 8 **START**: Start generation  
This bit is set and cleared by software and cleared by hardware when start is sent or PE=0.  
In Master Mode:  
0: No Start generation  
1: Repeated start generation  
In Slave mode:  
0: No Start generation  
1: Start generation when the bus is free
- Bit 7 **NOSTRETCH**: Clock stretching disable (Slave mode)  
This bit is used to disable clock stretching in slave mode when ADDR or BTF flag is set, until it is reset by software.  
0: Clock stretching enabled  
1: Clock stretching disabled
- Bit 6 **ENGC**: General call enable  
0: General call disabled. Address 00h is NACKed.  
1: General call enabled. Address 00h is ACKed.
- Bit 5 **ENPEC**: PEC enable  
0: PEC calculation disabled  
1: PEC calculation enabled
- Bit 4 **ENARP**: ARP enable  
0: ARP disable  
1: ARP enable  
SMBus Device default address recognized if SMBTYPE=0  
SMBus Host address recognized if SMBTYPE=1
- Bit 3 **SMBTYPE**: SMBus type  
0: SMBus Device  
1: SMBus Host

Bit 2 Reserved, must be kept at reset value

Bit 1 **SMBUS**: SMBus mode  
 0: I<sup>2</sup>C mode  
 1: SMBus mode

Bit 0 **PE**: Peripheral enable  
 0: Peripheral disable  
 1: Peripheral enable

*Note: If this bit is reset while a communication is on going, the peripheral is disabled at the end of the current communication, when back to IDLE state.  
 All bit resets due to PE=0 occur at the end of the communication.  
 In master mode, this bit must not be reset before the end of the communication.*

*Note: When the STOP, START or PEC bit is set, the software must not perform any write access to I2C\_CR1 before this bit is cleared by hardware. Otherwise there is a risk of setting a second STOP, START or PEC request.*

### 18.6.2 I<sup>2</sup>C Control register 2 (I2C\_CR2)

Address offset: 0x04  
 Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
Reserved			LAST	DMA EN	ITBUF EN	ITEVTEN	ITERR EN	Reserved			FREQ[5:0]					
			rw	rw	rw	rw	rw				rw	rw	rw	rw	rw	rw

Bits 15:13 Reserved, must be kept at reset value

Bit 12 **LAST**: DMA last transfer  
 0: Next DMA EOT is not the last transfer  
 1: Next DMA EOT is the last transfer

*Note: This bit is used in master receiver mode to permit the generation of a NACK on the last received data.*

Bit 11 **DMAEN**: DMA requests enable  
 0: DMA requests disabled  
 1: DMA request enabled when TxE=1 or RxNE =1

Bit 10 **ITBUFEN**: Buffer interrupt enable  
 0: TxE = 1 or RxNE = 1 does not generate any interrupt.  
 1: TxE = 1 or RxNE = 1 generates Event Interrupt (whatever the state of DMAEN)

Bit 9 **ITEVTEN**: Event interrupt enable

0: Event interrupt disabled

1: Event interrupt enabled

This interrupt is generated when:

- SB = 1 (Master)
- ADDR = 1 (Master/Slave)
- ADD10 = 1 (Master)
- STOPF = 1 (Slave)
- BTF = 1 with no TxE or RxNE event
- TxE event to 1 if ITBUFEN = 1
- RxNE event to 1 if ITBUFEN = 1

**ITERREN**: Error interrupt enable

0: Error interrupt disabled

1: Error interrupt enabled

This interrupt is generated when:

- BERR = 1
- ARLO = 1
- AF = 1
- OVR = 1
- PECERR = 1
- TIMEOUT = 1
- SMBALERT = 1

Bits 7:6 Reserved, must be kept at reset value

Bits 5:0 **FREQ[5:0]**: Peripheral clock frequency

The FREQ bits must be configured with the APB clock frequency value (I2C peripheral connected to APB). The FREQ field is used by the peripheral to generate data setup and hold times compliant with the I2C specifications. The minimum allowed frequency is 2 MHz, the maximum frequency is limited by the maximum APB1 frequency and cannot exceed 50 MHz (peripheral intrinsic maximum limit).

0b000000: Not allowed

0b000001: Not allowed

0b000010: 2 MHz

...

0b110010: 50 MHz

Higher than 0b100100: Not allowed

### 18.6.3 I<sup>2</sup>C Own address register 1 (I2C\_OAR1)

Address offset: 0x08  
 Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
ADD MODE	Reserved					ADD[9:8]		ADD[7:1]							ADD0	
r/w						r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w

Bit 15 **ADDMODE** Addressing mode (slave mode)  
 0: 7-bit slave address (10-bit address not acknowledged)  
 1: 10-bit slave address (7-bit address not acknowledged)

Bit 14 Should always be kept at 1 by software.

Bits 13:10 Reserved, must be kept at reset value

Bits 9:8 **ADD[9:8]**: Interface address  
 7-bit addressing mode: don't care  
 10-bit addressing mode: bits9:8 of address

Bits 7:1 **ADD[7:1]**: Interface address  
 bits 7:1 of address

Bit 0 **ADD0**: Interface address  
 7-bit addressing mode: don't care  
 10-bit addressing mode: bit 0 of address

### 18.6.4 I<sup>2</sup>C Own address register 2 (I2C\_OAR2)

Address offset: 0x0C  
 Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
Reserved								ADD2[7:1]							ENDUAL	
								r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w

Bits 15:8 Reserved, must be kept at reset value

Bits 7:1 **ADD2[7:1]**: Interface address  
 bits 7:1 of address in dual addressing mode

Bit 0 **ENDUAL**: Dual addressing mode enable  
 0: Only OAR1 is recognized in 7-bit addressing mode  
 1: Both OAR1 and OAR2 are recognized in 7-bit addressing mode



### 18.6.5 I<sup>2</sup>C Data register (I2C\_DR)

Address offset: 0x10  
 Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved								DR[7:0]							
								rw	rw	rw	rw	rw	rw	rw	rw

Bits 15:8 Reserved, must be kept at reset value

Bits 7:0 **DR[7:0]** 8-bit data register

Byte received or to be transmitted to the bus.

- Transmitter mode: Byte transmission starts automatically when a byte is written in the DR register. A continuous transmit stream can be maintained if the next data to be transmitted is put in DR once the transmission is started (TxE=1)
- Receiver mode: Received byte is copied into DR (RxNE=1). A continuous transmit stream can be maintained if DR is read before the next data byte is received (RxNE=1).

*Note:* In slave mode, the address is not copied into DR.

*Write collision is not managed (DR can be written if TxE=0).*

*If an ARLO event occurs on ACK pulse, the received byte is not copied into DR and so cannot be read.*

### 18.6.6 I<sup>2</sup>C Status register 1 (I2C\_SR1)

Address offset: 0x14  
 Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
SMB ALERT	TIME OUT	Res.	PEC ERR	OVR	AF	ARLO	BERR	TxE	RxNE	Res.	STOPF	ADD10	BTF	ADDR	SB
rc_w0	rc_w0		rc_w0	rc_w0	rc_w0	rc_w0	rc_w0	r	r		r	r	r	r	

- Bit 15 **SMBALERT**: SMBus alert
- In SMBus host mode:
    - 0: no SMBALERT
    - 1: SMBALERT event occurred on pin
  - In SMBus slave mode:
    - 0: no SMBALERT response address header
    - 1: SMBALERT response address header to SMBALERT LOW received
- Cleared by software writing 0, or by hardware when PE=0.
- Bit 14 **TIMEOUT**: Timeout or Tlow error
- 0: No timeout error
  - 1: SCL remained LOW for 25 ms (Timeout)
- or
- Master cumulative clock low extend time more than 10 ms (Tlow:mext)
- or
- Slave cumulative clock low extend time more than 25 ms (Tlow:sext)
- When set in slave mode: slave resets the communication and lines are released by hardware
- When set in master mode: Stop condition sent by hardware
- Cleared by software writing 0, or by hardware when PE=0.
- Note: This functionality is available only in SMBus mode.*
- Bit 13 Reserved, must be kept at reset value
- Bit 12 **PECERR**: PEC Error in reception
- 0: no PEC error: receiver returns ACK after PEC reception (if ACK=1)
  - 1: PEC error: receiver returns NACK after PEC reception (whatever ACK)
- Cleared by software writing 0, or by hardware when PE=0.
- Note: When the received CRC is wrong, PECERR is not set in slave mode if the PEC control bit is not set before the end of the CRC reception. Nevertheless, reading the PEC value determines whether the received CRC is right or wrong.
- Bit 11 **OVR**: Overrun/Underrun
- 0: No overrun/underrun
  - 1: Overrun or underrun
- Set by hardware in slave mode when NOSTRETCH=1 and:
- In reception when a new byte is received (including ACK pulse) and the DR register has not been read yet. New received byte is lost.
  - In transmission when a new byte should be sent and the DR register has not been written yet. The same byte is sent twice.
- Cleared by software writing 0, or by hardware when PE=0.
- Note: If the DR write occurs very close to SCL rising edge, the sent data is unspecified and a hold timing error occurs*
- Bit 10 **AF**: Acknowledge failure
- 0: No acknowledge failure
  - 1: Acknowledge failure
- Set by hardware when no acknowledge is returned.
- Cleared by software writing 0, or by hardware when PE=0.

- Bit 9 **ARLO**: Arbitration lost (master mode)
- 0: No Arbitration Lost detected
  - 1: Arbitration Lost detected
- Set by hardware when the interface loses the arbitration of the bus to another master
- Cleared by software writing 0, or by hardware when PE=0.
- After an ARLO event the interface switches back automatically to Slave mode (MSL=0).
- Note: In SMBUS, the arbitration on the data in slave mode occurs only during the data phase, or the acknowledge transmission (not on the address acknowledge).*
- Bit 8 **BERR**: Bus error
- 0: No misplaced Start or Stop condition
  - 1: Misplaced Start or Stop condition
- Set by hardware when the interface detects an SDA rising or falling edge while SCL is high, occurring in a non-valid position during a byte transfer.
  - Cleared by software writing 0, or by hardware when PE=0.
- Bit 7 **TxE**: Data register empty (transmitters)
- 0: Data register not empty
  - 1: Data register empty
- Set when DR is empty in transmission. TxE is not set during address phase.
  - Cleared by software writing to the DR register or by hardware after a start or a stop condition or when PE=0.
- TxE is not set if either a NACK is received, or if next byte to be transmitted is PEC (PEC=1)
- Note: TxE is not cleared by writing the first data being transmitted, or by writing data when BTF is set, as in both cases the data register is still empty.*
- Bit 6 **RxNE**: Data register not empty (receivers)
- 0: Data register empty
  - 1: Data register not empty
- Set when data register is not empty in receiver mode. RxNE is not set during address phase.
  - Cleared by software reading or writing the DR register or by hardware when PE=0.
- RxNE is not set in case of ARLO event.
- Note: RxNE is not cleared by reading data when BTF is set, as the data register is still full.*
- Bit 5 Reserved, must be kept at reset value
- Bit 4 **STOPF**: Stop detection (slave mode)
- 0: No Stop condition detected
  - 1: Stop condition detected
- Set by hardware when a Stop condition is detected on the bus by the slave after an acknowledge (if ACK=1).
  - Cleared by software reading the SR1 register followed by a write in the CR1 register, or by hardware when PE=0
- Note: The STOPF bit is not set after a NACK reception.  
It is recommended to perform the complete clearing sequence (READ SR1 then WRITE CR1) after the STOPF is set. Refer to [Figure 163: Transfer sequence diagram for slave receiver on page 472](#).*

**Bit 3 ADD10:** 10-bit header sent (Master mode)

0: No ADD10 event occurred.

1: Master has sent first address byte (header).

- Set by hardware when the master has sent the first byte in 10-bit address mode.
- Cleared by software reading the SR1 register followed by a write in the DR register of the second address byte, or by hardware when PE=0.

*Note: ADD10 bit is not set after a NACK reception*

**Bit 2 BTF:** Byte transfer finished

0: Data byte transfer not done

1: Data byte transfer succeeded

- Set by hardware when NOSTRETCH=0 and:
  - In reception when a new byte is received (including ACK pulse) and DR has not been read yet (RxNE=1).
  - In transmission when a new byte should be sent and DR has not been written yet (TxE=1).
- Cleared by software by either a read or write in the DR register or by hardware after a start or a stop condition in transmission or when PE=0.

*Note: The BTF bit is not set after a NACK reception*

*The BTF bit is not set if next byte to be transmitted is the PEC (TRA=1 in I2C\_SR2 register and PEC=1 in I2C\_CR1 register)*

**Bit 1 ADDR:** Address sent (master mode)/matched (slave mode)

This bit is cleared by software reading SR1 register followed reading SR2, or by hardware when PE=0.

Address matched (Slave)

0: Address mismatched or not received.

1: Received address matched.

- Set by hardware as soon as the received slave address matched with the OAR registers content or a general call or a SMBus Device Default Address or SMBus Host or SMBus Alert is recognized. (when enabled depending on configuration).

*Note: In slave mode, it is recommended to perform the complete clearing sequence (READ SR1 then READ SR2) after ADDR is set. Refer to [Figure 163: Transfer sequence diagram for slave receiver on page 472](#).*

Address sent (Master)

0: No end of address transmission

1: End of address transmission

- For 10-bit addressing, the bit is set after the ACK of the 2nd byte.
- For 7-bit addressing, the bit is set after the ACK of the byte.

*Note: ADDR is not set after a NACK reception*

**Bit 0 SB:** Start bit (Master mode)

0: No Start condition

1: Start condition generated.

- Set when a Start condition generated.
- Cleared by software by reading the SR1 register followed by writing the DR register, or by hardware when PE=0

### 18.6.7 I<sup>2</sup>C Status register 2 (I2C\_SR2)

Address offset: 0x18  
 Reset value: 0x0000

*Note:* Reading I2C\_SR2 after reading I2C\_SR1 clears the ADDR flag, even if the ADDR flag was set after reading I2C\_SR1. Consequently, I2C\_SR2 must be read only when ADDR is found set in I2C\_SR1 or when the STOPF bit is cleared.

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
PEC[7:0]								DUALF	SMB HOST	SMBDE FAULT	GEN CALL	Res.	TRA	BUSY	MSL
r	r	r	r	r	r	r	r	r	r	r	r		r	r	r

Bits 15:8 **PEC[7:0]** Packet error checking register

This register contains the internal PEC when ENPEC=1.

Bit 7 **DUALF**: Dual flag (Slave mode)

- 0: Received address matched with OAR1
- 1: Received address matched with OAR2

– Cleared by hardware after a Stop condition or repeated Start condition, or when PE=0.

Bit 6 **SMBHOST**: SMBus host header (Slave mode)

- 0: No SMBus Host address
- 1: SMBus Host address received when SMBTYPE=1 and ENARP=1.

– Cleared by hardware after a Stop condition or repeated Start condition, or when PE=0.

Bit 5 **SMBDEFAULT**: SMBus device default address (Slave mode)

- 0: No SMBus Device Default address
- 1: SMBus Device Default address received when ENARP=1

– Cleared by hardware after a Stop condition or repeated Start condition, or when PE=0.

Bit 4 **GENCALL**: General call address (Slave mode)

- 0: No General Call
- 1: General Call Address received when ENGC=1

– Cleared by hardware after a Stop condition or repeated Start condition, or when PE=0.

Bit 3 Reserved, must be kept at reset value

Bit 2 **TRA**: Transmitter/receiver

- 0: Data bytes received
- 1: Data bytes transmitted

This bit is set depending on the R/W bit of the address byte, at the end of total address phase.

It is also cleared by hardware after detection of Stop condition (STOPF=1), repeated Start condition, loss of bus arbitration (ARLO=1), or when PE=0.

Bit 1 **BUSY**: Bus busy

- 0: No communication on the bus
- 1: Communication ongoing on the bus

- Set by hardware on detection of SDA or SCL low
- cleared by hardware on detection of a Stop condition.

It indicates a communication in progress on the bus. This information is still updated when the interface is disabled (PE=0).

Bit 0 **MSL**: Master/slave

- 0: Slave Mode
- 1: Master Mode

- Set by hardware as soon as the interface is in Master mode (SB=1).
- Cleared by hardware after detecting a Stop condition on the bus or a loss of arbitration (ARLO=1), or by hardware when PE=0.

*Note:* Reading I2C\_SR2 after reading I2C\_SR1 clears the ADDR flag, even if the ADDR flag was set after reading I2C\_SR1. Consequently, I2C\_SR2 must be read only when ADDR is found set in I2C\_SR1 or when the STOPF bit is cleared.

### 18.6.8 I<sup>2</sup>C Clock control register (I2C\_CCR)

Address offset: 0x1C

Reset value: 0x0000

*Note:*  $f_{PCLK1}$  must be at least 2 MHz to achieve Sm mode I<sup>2</sup>C frequencies. It must be at least 4 MHz to achieve Fm mode I<sup>2</sup>C frequencies. It must be a multiple of 10MHz to reach the 400 kHz maximum I<sup>2</sup>C Fm mode clock.

The CCR register must be configured only when the I2C is disabled (PE = 0).

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
F/S	DUTY	Reserved			CCR[11:0]										
rw	rw				rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bit 15 **F/S**: I2C master mode selection

- 0: Sm mode I2C
- 1: Fm mode I2C

Bit 14 **DUTY**: Fm mode duty cycle  
 0: Fm mode  $t_{low}/t_{high} = 2$   
 1: Fm mode  $t_{low}/t_{high} = 16/9$  (see CCR)

Bits 13:12 Reserved, must be kept at reset value

Bits 11:0 **CCR[11:0]**: Clock control register in Fm/Sm mode (Master mode)

Controls the SCL clock in master mode.

Sm mode or SMBus:

$$T_{high} = CCR * T_{PCLK1}$$

$$T_{low} = CCR * T_{PCLK1}$$

Fm mode:

If DUTY = 0:

$$T_{high} = CCR * T_{PCLK1}$$

$$T_{low} = 2 * CCR * T_{PCLK1}$$

If DUTY = 1: (to reach 400 kHz)

$$T_{high} = 9 * CCR * T_{PCLK1}$$

$$T_{low} = 16 * CCR * T_{PCLK1}$$

For instance: in Sm mode, to generate a 100 kHz SCL frequency:

If FREQR = 08,  $T_{PCLK1} = 125$  ns so CCR must be programmed with 0x28

(0x28 <=> 40d x 125 ns = 5000 ns.)

*Note: The minimum allowed value is 0x04, except in FAST DUTY mode where the minimum allowed value is 0x01*

$t_{high} = t_r(SCL) + t_w(SCLH)$ . See device datasheet for the definitions of parameters.

$t_{low} = t_f(SCL) + t_w(SCLL)$ . See device datasheet for the definitions of parameters.

I<sup>2</sup>C communication speed,  $f_{SCL} \sim 1/(t_{high} + t_{low})$ . The real frequency may differ due to the analog noise filter input delay.

The CCR register must be configured only when the I<sup>2</sup>C is disabled (PE = 0).

### 18.6.9 I<sup>2</sup>C TRISE register (I2C\_TRISE)

Address offset: 0x20

Reset value: 0x0002

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved										TRISE[5:0]					
										rw	rw	rw	rw	rw	rw

Bits 15:6 Reserved, must be kept at reset value

Bits 5:0 **TRISE[5:0]**: Maximum rise time in Fm/Sm mode (Master mode)

These bits should provide the maximum duration of the SCL feedback loop in master mode.

The purpose is to keep a stable SCL frequency whatever the SCL rising edge duration.

These bits must be programmed with the maximum SCL rise time given in the I<sup>2</sup>C bus specification, incremented by 1.

For instance: in Sm mode, the maximum allowed SCL rise time is 1000 ns.

If, in the I2C\_CR2 register, the value of FREQ[5:0] bits is equal to 0x08 and  $T_{PCLK1} = 125$  ns therefore the TRISE[5:0] bits must be programmed with 09h.

(1000 ns / 125 ns = 8 + 1)

The filter value can also be added to TRISE[5:0].

If the result is not an integer, TRISE[5:0] must be programmed with the integer part, in order to respect the  $t_{HIGH}$  parameter.

*Note: TRISE[5:0] must be configured only when the I2C is disabled (PE = 0).*

### 18.6.10 I<sup>2</sup>C FLTR register (I2C\_FLTR)

Address offset: 0x24

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
Reserved											ANOFF	DNF[3:0]				
											rw	rw	rw	rw	rw	

Bits 15:5 Reserved, must be kept at reset value

Bit 4 **ANOFF**: Analog noise filter OFF

0: Analog noise filter enable

1: Analog noise filter disable

*Note: ANOFF must be configured only when the I2C is disabled (PE = 0).*

Bits 3:0 **DNF[3:0]**: Digital noise filter

These bits are used to configure the digital noise filter on SDA and SCL inputs. The digital filter will suppress the spikes with a length of up to DNF[3:0] \* TPCLK1.

0000: Digital noise filter disable

0001: Digital noise filter enabled and filtering capability up to 1\* TPCLK1.

...

1111: Digital noise filter enabled and filtering capability up to 15\* TPCLK1.

*Note: DNF[3:0] must be configured only when the I2C is disabled (PE = 0). If the analog filter is also enabled, the digital filter is added to the analog filter.*



### 18.6.11 I<sup>2</sup>C register map

The table below provides the I<sup>2</sup>C register map and reset values.

**Table 72. I<sup>2</sup>C register map and reset values**

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0				
0x00	I2C_CR1	Reserved																	SWRST	Reserved	ALERT	PEC	POS	ACK	STOP	START	NOSTRETCH	ENG	ENPEC	ENARP	SMBTYPE	Reserved	SMBUS	PE			
	Reset value																		0		0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x04	I2C_CR2	Reserved																			LAST	DMAEN	ITBUFEN	ITEVTEN	ITERREN	Reserved	FREQ[5:0]										
	Reset value																				0	0	0	0	0	Reserved	0	0	0	0	0	0	0	0	0	0	
0x08	I2C_OAR1	Reserved																	ADDMODE	Reserved					ADD[9:8]		ADD[7:1]					ADD0					
	Reset value																		0						0	0	0	0	0	0	0	0	0	0			
0x0C	I2C_OAR2	Reserved																	ADD2[7:1]					ENDUAL													
	Reset value																		0	0	0	0	0	0	0	0	0	0	0	0							
0x10	I2C_DR	Reserved																	DR[7:0]																		
	Reset value																		0	0	0	0	0	0	0	0	0	0	0	0							
0x14	I2C_SR1	Reserved																	SMBALERT	TIMEOUT	Reserved	PECERR	OVR	AF	ARLO	BERR	TxE	RxNE	Reserved	STOPF	ADD10	BTF	ADDR	SB			
	Reset value																		0	0		0	0	0	0	0	0	0	0	0	0	0	0	0			
0x18	I2C_SR2	Reserved																	PEC[7:0]					DUALF	SMBHOST	SMBDEFAULT	GENCALL	Reserved	TRA	BUSY	MSL						
	Reset value																		0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0			
0x1C	I2C_CCR	Reserved																	F/S	DUTY	Reserved	CCR[11:0]															
	Reset value																		0	0	Reserved	0	0	0	0	0	0	0	0	0	0	0	0	0	0		
0x20	I2C_TRISE	Reserved																	TRISE[5:0]																		
	Reset value																		0	0	0	0	0	0	0	0	0	0	0	0	0	0	0				
0x24	I2C_FLTR	Reserved																	ANOFF	DNF[3:0]																	
	Reset value																		0	0	0	0	0	0	0	0	0	0	0	0	0	0					

Refer to [Table 1 on page 38](#) for the register boundary addresses table.



## 19 Universal synchronous asynchronous receiver transmitter (USART)

### 19.1 USART introduction

The universal synchronous asynchronous receiver transmitter (USART) offers a flexible means of full-duplex data exchange with external equipment requiring an industry standard NRZ asynchronous serial data format. The USART offers a very wide range of baud rates using a fractional baud rate generator.

It supports synchronous one-way communication and half-duplex single wire communication. It also supports the LIN (local interconnection network), Smartcard Protocol and IrDA (infrared data association) SIR ENDEC specifications, and modem operations (CTS/RTS). It allows multiprocessor communication.

High speed data communication is possible by using the DMA for multibuffer configuration.

### 19.2 USART main features

- Full duplex, asynchronous communications
- NRZ standard format (Mark/Space)
- Configurable oversampling method by 16 or by 8 to give flexibility between speed and clock tolerance
- Fractional baud rate generator systems
  - Common programmable transmit and receive baud rate (refer to the datasheets for the value of the baud rate at the maximum APB frequency).
- Programmable data word length (8 or 9 bits)
- Configurable stop bits - support for 1 or 2 stop bits
- LIN Master Synchronous Break send capability and LIN slave break detection capability
  - 13-bit break generation and 10/11 bit break detection when USART is hardware configured for LIN
- Transmitter clock output for synchronous transmission
- IrDA SIR encoder decoder
  - Support for 3/16 bit duration for normal mode
- Smartcard emulation capability
  - The Smartcard interface supports the asynchronous protocol Smartcards as defined in the ISO 7816-3 standards
  - 0.5, 1.5 stop bits for Smartcard operation
- Single-wire half-duplex communication
- Configurable multibuffer communication using DMA (direct memory access)
  - Buffering of received/transmitted bytes in reserved SRAM using centralized DMA
- Separate enable bits for transmitter and receiver
- Transfer detection flags:
  - Receive buffer full

- Transmit buffer empty
- End of transmission flags
- Parity control:
  - Transmits parity bit
  - Checks parity of received data byte
- Four error detection flags:
  - Overrun error
  - Noise detection
  - Frame error
  - Parity error
- Ten interrupt sources with flags:
  - CTS changes
  - LIN break detection
  - Transmit data register empty
  - Transmission complete
  - Receive data register full
  - Idle line received
  - Overrun error
  - Framing error
  - Noise error
  - Parity error
- Multiprocessor communication - enter into mute mode if address match does not occur
- Wake up from mute mode (by idle line detection or address mark detection)
- Two receiver wakeup modes: Address bit (MSB, 9<sup>th</sup> bit), Idle line

### 19.3 USART functional description

The interface is externally connected to another device by three pins (see [Figure 167](#)). Any USART bidirectional communication requires a minimum of two pins: Receive Data In (RX) and Transmit Data Out (TX):

**RX:** Receive Data Input is the serial data input. Oversampling techniques are used for data recovery by discriminating between valid incoming data and noise.

**TX:** Transmit Data Output. When the transmitter is disabled, the output pin returns to its I/O port configuration. When the transmitter is enabled and nothing is to be transmitted, the TX pin is at high level. In single-wire and smartcard modes, this I/O is used to transmit and receive the data (at USART level, data are then received on SW\_RX).

Through these pins, serial data is transmitted and received in normal USART mode as frames comprising:

- An Idle Line prior to transmission or reception
- A start bit
- A data word (8 or 9 bits) least significant bit first
- 0.5, 1, 1.5, 2 Stop bits indicating that the frame is complete
- This interface uses a fractional baud rate generator - with a 12-bit mantissa and 4-bit fraction
- A status register (USART\_SR)
- Data Register (USART\_DR)
- A baud rate register (USART\_BRR) - 12-bit mantissa and 4-bit fraction.
- A Guardtime Register (USART\_GTPR) in case of Smartcard mode.

Refer to [Section 19.6: USART registers on page 542](#) for the definitions of each bit.

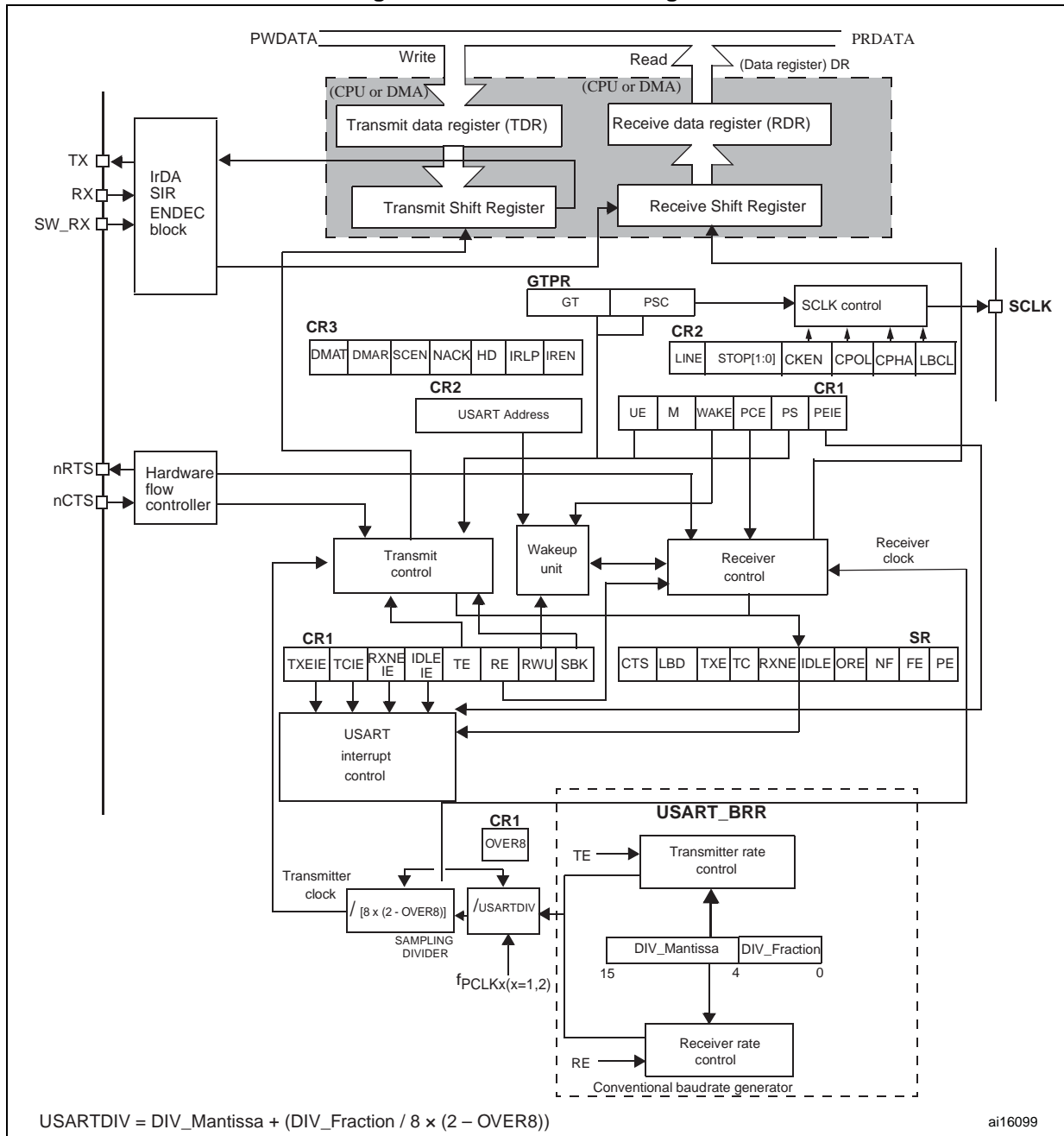
The following pin is required to interface in synchronous mode:

- **SCLK:** Transmitter clock output. This pin outputs the transmitter data clock for synchronous transmission corresponding to SPI master mode (no clock pulses on start bit and stop bit, and a software option to send a clock pulse on the last data bit). In parallel data can be received synchronously on RX. This can be used to control peripherals that have shift registers (e.g. LCD drivers). The clock phase and polarity are software programmable. In smartcard mode, SCLK can provide the clock to the smartcard.

The following pins are required in Hardware flow control mode:

- **nCTS:** Clear To Send blocks the data transmission at the end of the current transfer when high
- **nRTS:** Request to send indicates that the USART is ready to receive a data (when low).

Figure 167. USART block diagram



### 19.3.1 USART character description

Word length may be selected as being either 8 or 9 bits by programming the M bit in the USART\_CR1 register (see [Figure 168](#)).

The TX pin is in low state during the start bit. It is in high state during the stop bit.

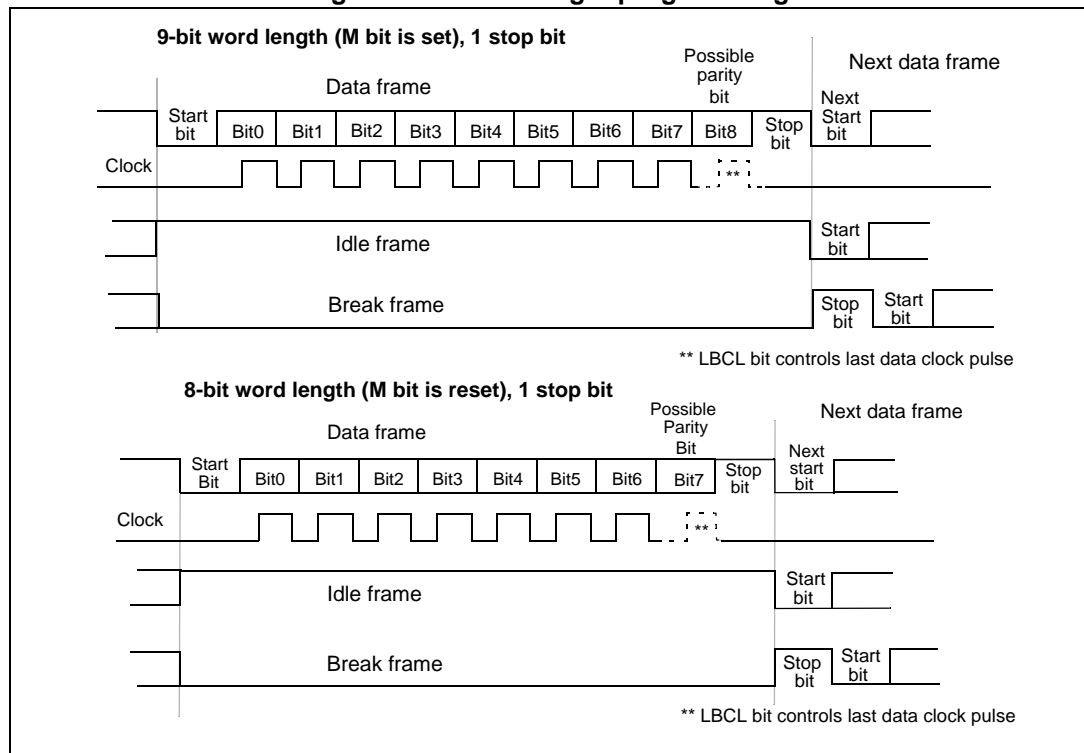
An **Idle character** is interpreted as an entire frame of “1”s followed by the start bit of the next frame which contains data (The number of “1” ‘s will include the number of stop bits).

A **Break character** is interpreted on receiving “0”s for a frame period. At the end of the break frame the transmitter inserts either 1 or 2 stop bits (logic “1” bit) to acknowledge the start bit.

Transmission and reception are driven by a common baud rate generator, the clock for each is generated when the enable bit is set respectively for the transmitter and receiver.

The details of each block is given below.

**Figure 168. Word length programming**



### 19.3.2 Transmitter

The transmitter can send data words of either 8 or 9 bits depending on the M bit status. When the transmit enable bit (TE) is set, the data in the transmit shift register is output on the TX pin and the corresponding clock pulses are output on the SCLK pin.

#### Character transmission

During an USART transmission, data shifts out least significant bit first on the TX pin. In this mode, the USART\_DR register consists of a buffer (TDR) between the internal bus and the transmit shift register (see [Figure 167](#)).

Every character is preceded by a start bit which is a logic level low for one bit period. The character is terminated by a configurable number of stop bits.

The following stop bits are supported by USART: 0.5, 1, 1.5 and 2 stop bits.

*Note: The TE bit should not be reset during transmission of data. Resetting the TE bit during the transmission will corrupt the data on the TX pin as the baud rate counters will get frozen. The current data being transmitted will be lost.*

*An idle frame will be sent after the TE bit is enabled.*

#### Configurable stop bits

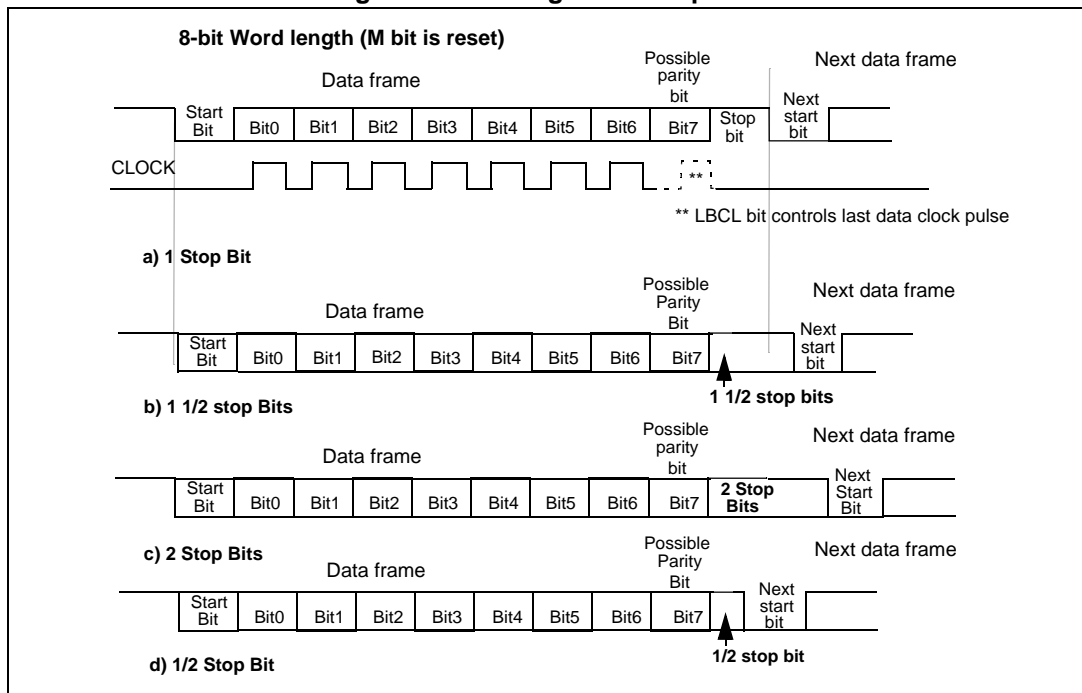
The number of stop bits to be transmitted with every character can be programmed in Control register 2, bits 13,12.

- **1 stop bit:** This is the default value of number of stop bits.
- **2 Stop bits:** This will be supported by normal USART, single-wire and modem modes.
- **0.5 stop bit:** To be used when receiving data in Smartcard mode.
- **1.5 stop bits:** To be used when transmitting and receiving data in Smartcard mode.

An idle frame transmission will include the stop bits.

A break transmission will be 10 low bits followed by the configured number of stop bits (when  $m = 0$ ) and 11 low bits followed by the configured number of stop bits (when  $m = 1$ ). It is not possible to transmit long breaks (break of length greater than 10/11 low bits).

Figure 169. Configurable stop bits



Procedure:

1. Enable the USART by writing the UE bit in USART\_CR1 register to 1.
2. Program the M bit in USART\_CR1 to define the word length.
3. Program the number of stop bits in USART\_CR2.
4. Select DMA enable (DMAT) in USART\_CR3 if Multi buffer Communication is to take place. Configure the DMA register as explained in multibuffer communication.
5. Select the desired baud rate using the USART\_BRR register.
6. Set the TE bit in USART\_CR1 to send an idle frame as first transmission.
7. Write the data to send in the USART\_DR register (this clears the TXE bit). Repeat this for each data to be transmitted in case of single buffer.
8. After writing the last data into the USART\_DR register, wait until TC=1. This indicates that the transmission of the last frame is complete. This is required for instance when the USART is disabled or enters the Halt mode to avoid corrupting the last transmission.

### Single byte communication

Clearing the TXE bit is always performed by a write to the data register.

The TXE bit is set by hardware and it indicates:

- The data has been moved from TDR to the shift register and the data transmission has started.
- The TDR register is empty.
- The next data can be written in the USART\_DR register without overwriting the previous data.

This flag generates an interrupt if the TXEIE bit is set.



When a transmission is taking place, a write instruction to the USART\_DR register stores the data in the TDR register and which is copied in the shift register at the end of the current transmission.

When no transmission is taking place, a write instruction to the USART\_DR register places the data directly in the shift register, the data transmission starts, and the TXE bit is immediately set.

If a frame is transmitted (after the stop bit) and the TXE bit is set, the TC bit goes high. An interrupt is generated if the TCIE bit is set in the USART\_CR1 register.

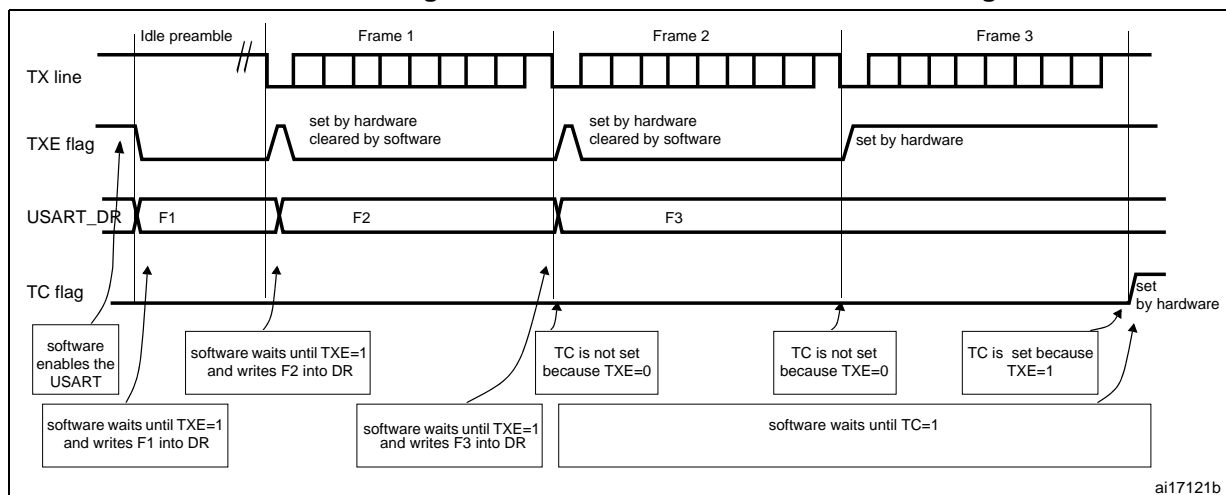
After writing the last data into the USART\_DR register, it is mandatory to wait for TC=1 before disabling the USART or causing the microcontroller to enter the low-power mode (see [Figure 170: TC/TXE behavior when transmitting](#)).

The TC bit is cleared by the following software sequence:

1. A read from the USART\_SR register
2. A write to the USART\_DR register

*Note: The TC bit can also be cleared by writing a '0' to it. This clearing sequence is recommended only for Multibuffer communication.*

**Figure 170. TC/TXE behavior when transmitting**



**Break characters**

Setting the SBK bit transmits a break character. The break frame length depends on the M bit (see [Figure 168](#)).

If the SBK bit is set to '1 a break character is sent on the TX line after completing the current character transmission. This bit is reset by hardware when the break character is completed (during the stop bit of the break character). The USART inserts a logic 1 bit at the end of the last break frame to guarantee the recognition of the start bit of the next frame.

*Note: If the software resets the SBK bit before the commencement of break transmission, the break character will not be transmitted. For two consecutive breaks, the SBK bit should be set after the stop bit of the previous break.*

**Idle characters**

Setting the TE bit drives the USART to send an idle frame before the first data frame.

### 19.3.3 Receiver

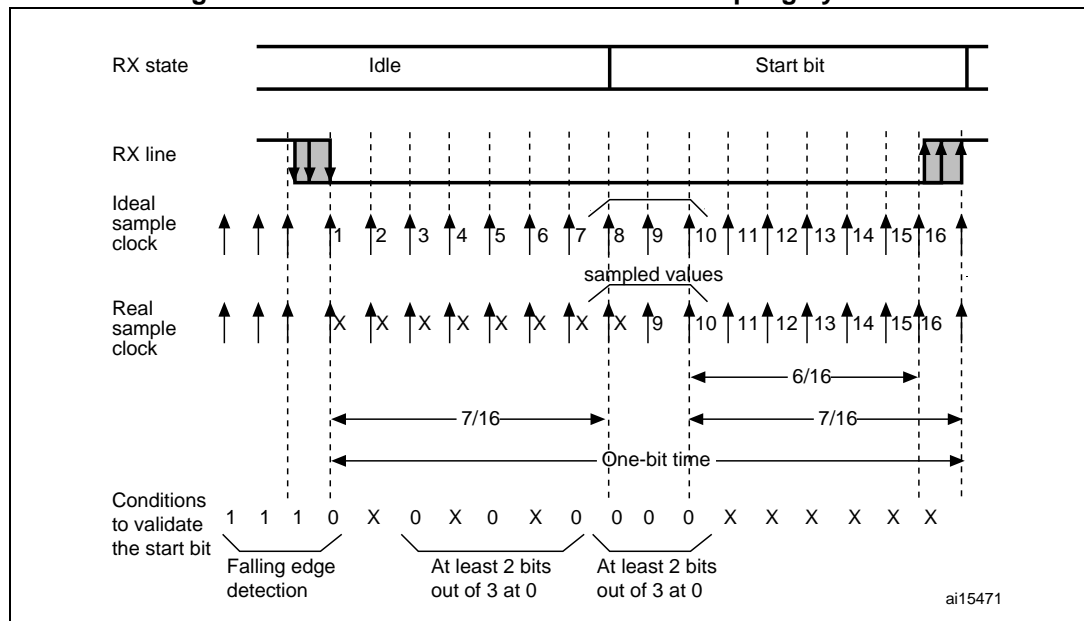
The USART can receive data words of either 8 or 9 bits depending on the M bit in the USART\_CR1 register.

#### Start bit detection

The start bit detection sequence is the same when oversampling by 16 or by 8.

In the USART, the start bit is detected when a specific sequence of samples is recognized. This sequence is: 1 1 1 0 X 0 X 0 X 0 0 0 0.

Figure 171. Start bit detection when oversampling by 16 or 8



**Note:** If the sequence is not complete, the start bit detection aborts and the receiver returns to the idle state (no flag is set) where it waits for a falling edge.

The start bit is confirmed (RXNE flag set, interrupt generated if RXNEIE=1) if the 3 sampled bits are at 0 (first sampling on the 3rd, 5th and 7th bits finds the 3 bits at 0 and second sampling on the 8th, 9th and 10th bits also finds the 3 bits at 0).

The start bit is validated (RXNE flag set, interrupt generated if RXNEIE=1) but the NE noise flag is set if, for both samplings, at least 2 out of the 3 sampled bits are at 0 (sampling on the 3rd, 5th and 7th bits and sampling on the 8th, 9th and 10th bits). If this condition is not met, the start detection aborts and the receiver returns to the idle state (no flag is set).

If, for one of the samplings (sampling on the 3rd, 5th and 7th bits or sampling on the 8th, 9th and 10th bits), 2 out of the 3 bits are found at 0, the start bit is validated but the NE noise flag bit is set.

## Character reception

During an USART reception, data shifts in least significant bit first through the RX pin. In this mode, the USART\_DR register consists of a buffer (RDR) between the internal bus and the received shift register.

Procedure:

1. Enable the USART by writing the UE bit in USART\_CR1 register to 1.
2. Program the M bit in USART\_CR1 to define the word length.
3. Program the number of stop bits in USART\_CR2.
4. Select DMA enable (DMAR) in USART\_CR3 if multibuffer communication is to take place. Configure the DMA register as explained in multibuffer communication. STEP 3
5. Select the desired baud rate using the baud rate register USART\_BRR
6. Set the RE bit USART\_CR1. This enables the receiver which begins searching for a start bit.

When a character is received

- The RXNE bit is set. It indicates that the content of the shift register is transferred to the RDR. In other words, data has been received and can be read (as well as its associated error flags).
- An interrupt is generated if the RXNEIE bit is set.
- The error flags can be set if a frame error, noise or an overrun error has been detected during reception.
- In multibuffer, RXNE is set after every byte received and is cleared by the DMA read to the Data Register.
- In single buffer mode, clearing the RXNE bit is performed by a software read to the USART\_DR register. The RXNE flag can also be cleared by writing a zero to it. The RXNE bit must be cleared before the end of the reception of the next character to avoid an overrun error.

*Note:* The RE bit should not be reset while receiving data. If the RE bit is disabled during reception, the reception of the current byte will be aborted.

## Break character

When a break character is received, the USART handles it as a framing error.

## Idle character

When an idle frame is detected, there is the same procedure as a data received character plus an interrupt if the IDLEIE bit is set.

### Overrun error

An overrun error occurs when a character is received when RXNE has not been reset. Data can not be transferred from the shift register to the RDR register until the RXNE bit is cleared.

The RXNE flag is set after every byte received. An overrun error occurs if RXNE flag is set when the next data is received or the previous DMA request has not been serviced. When an overrun error occurs:

- The ORE bit is set.
- The RDR content will not be lost. The previous data is available when a read to USART\_DR is performed.
- The shift register will be overwritten. After that point, any data received during overrun is lost.
- An interrupt is generated if either the RXNEIE bit is set or both the EIE and DMAR bits are set.
- The ORE bit is reset by a read to the USART\_SR register followed by a USART\_DR register read operation.

*Note:* The ORE bit, when set, indicates that at least 1 data has been lost. There are two possibilities:

- if RXNE=1, then the last valid data is stored in the receive register RDR and can be read,
- if RXNE=0, then it means that the last valid data has already been read and thus there is nothing to be read in the RDR. This case can occur when the last valid data is read in the RDR at the same time as the new (and lost) data is received. It may also occur when the new data is received during the reading sequence (between the USART\_SR register read access and the USART\_DR read access).

### Selecting the proper oversampling method

The receiver implements different user-configurable oversampling techniques (except in synchronous mode) for data recovery by discriminating between valid incoming data and noise.

The oversampling method can be selected by programming the OVER8 bit in the USART\_CR1 register and can be either 16 or 8 times the baud rate clock ([Figure 172](#) and [Figure 173](#)).

Depending on the application:

- select oversampling by 8 (OVER8=1) to achieve higher speed (up to  $f_{PCLK}/8$ ). In this case the maximum receiver tolerance to clock deviation is reduced (refer to [Section 19.3.5: USART receiver tolerance to clock deviation on page 524](#))
- select oversampling by 16 (OVER8=0) to increase the tolerance of the receiver to clock deviations. In this case, the maximum speed is limited to maximum  $f_{PCLK}/16$

Programming the ONEBIT bit in the USART\_CR3 register selects the method used to evaluate the logic level. There are two options:

- the majority vote of the three samples in the center of the received bit. In this case, when the 3 samples used for the majority vote are not equal, the NF bit is set
- a single sample in the center of the received bit

Depending on the application:

- select the three samples’ majority vote method (ONEBIT=0) when operating in a noisy environment and reject the data when a noise is detected (refer to [Figure 73](#)) because this indicates that a glitch occurred during the sampling.
- select the single sample method (ONEBIT=1) when the line is noise-free to increase the receiver’s tolerance to clock deviations (see [Section 19.3.5: USART receiver tolerance to clock deviation on page 524](#)). In this case the NF bit will never be set.

When noise is detected in a frame:

- The NF bit is set at the rising edge of the RXNE bit.
- The invalid data is transferred from the Shift register to the USART\_DR register.
- No interrupt is generated in case of single byte communication. However this bit rises at the same time as the RXNE bit which itself generates an interrupt. In case of multibuffer communication an interrupt will be issued if the EIE bit is set in the USART\_CR3 register.

The NF bit is reset by a USART\_SR register read operation followed by a USART\_DR register read operation.

*Note: Oversampling by 8 is not available in the Smartcard, IrDA and LIN modes. In those modes, the OVER8 bit is forced to ‘0 by hardware.*

**Figure 172. Data sampling when oversampling by 16**

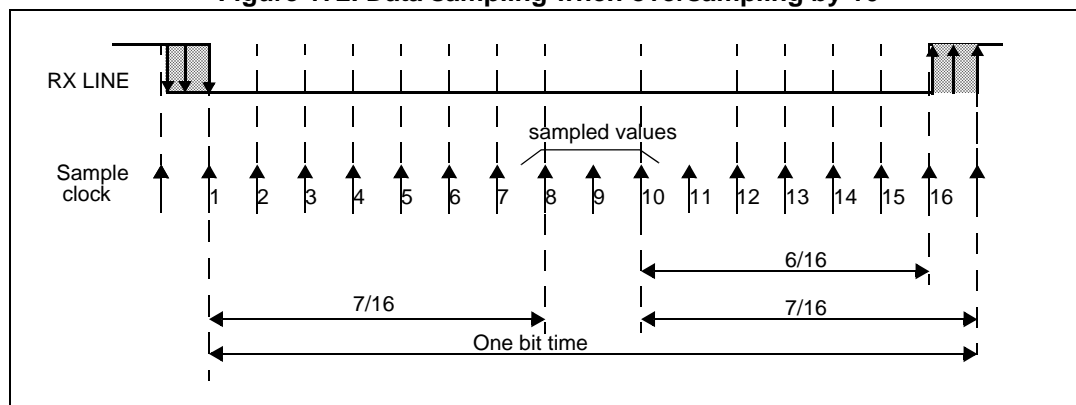


Figure 173. Data sampling when oversampling by 8

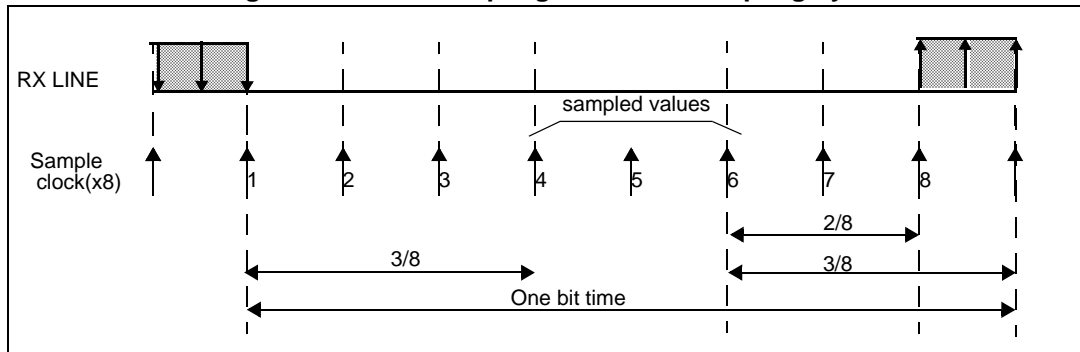


Table 73. Noise detection from sampled data

Sampled value	NE status	Received bit value
000	0	0
001	1	0
010	1	0
011	1	1
100	1	0
101	1	1
110	1	1
111	0	1

**Framing error**

A framing error is detected when:

The stop bit is not recognized on reception at the expected time, following either a de-synchronization or excessive noise.

When the framing error is detected:

- The FE bit is set by hardware
- The invalid data is transferred from the Shift register to the USART\_DR register.
- No interrupt is generated in case of single byte communication. However this bit rises at the same time as the RXNE bit which itself generates an interrupt. In case of multibuffer communication an interrupt will be issued if the EIE bit is set in the USART\_CR3 register.

The FE bit is reset by a USART\_SR register read operation followed by a USART\_DR register read operation.

### Configurable stop bits during reception

The number of stop bits to be received can be configured through the control bits of Control Register 2 - it can be either 1 or 2 in normal mode and 0.5 or 1.5 in Smartcard mode.

1. **0.5 stop bit (reception in Smartcard mode):** No sampling is done for 0.5 stop bit. As a consequence, no framing error and no break frame can be detected when 0.5 stop bit is selected.
2. **1 stop bit:** Sampling for 1 stop Bit is done on the 8th, 9th and 10th samples.
3. **1.5 stop bits (Smartcard mode):** When transmitting in smartcard mode, the device must check that the data is correctly sent. Thus the receiver block must be enabled (RE =1 in the USART\_CR1 register) and the stop bit is checked to test if the smartcard has detected a parity error. In the event of a parity error, the smartcard forces the data signal low during the sampling - NACK signal-, which is flagged as a framing error. Then, the FE flag is set with the RXNE at the end of the 1.5 stop bit. Sampling for 1.5 stop bits is done on the 16th, 17th and 18th samples (1 baud clock period after the beginning of the stop bit). The 1.5 stop bit can be decomposed into 2 parts: one 0.5 baud clock period during which nothing happens, followed by 1 normal stop bit period during which sampling occurs halfway through. Refer to [Section 19.3.11: Smartcard on page 533](#) for more details.
4. **2 stop bits:** Sampling for 2 stop bits is done on the 8th, 9th and 10th samples of the first stop bit. If a framing error is detected during the first stop bit the framing error flag will be set. The second stop bit is not checked for framing error. The RXNE flag will be set at the end of the first stop bit.

### 19.3.4 Fractional baud rate generation

The baud rate for the receiver and transmitter (Rx and Tx) are both set to the same value as programmed in the Mantissa and Fraction values of USARTDIV.

#### Equation 1: Baud rate for standard USART (SPI mode included)

$$\text{Tx/Rx baud} = \frac{f_{\text{CK}}}{8 \times (2 - \text{OVER8}) \times \text{USARTDIV}}$$

#### Equation 2: Baud rate in Smartcard, LIN and IrDA modes

$$\text{Tx/Rx baud} = \frac{f_{\text{CK}}}{16 \times \text{USARTDIV}}$$

USARTDIV is an unsigned fixed point number that is coded on the USART\_BRR register.

- When OVER8=0, the fractional part is coded on 4 bits and programmed by the DIV\_fraction[3:0] bits in the USART\_BRR register
- When OVER8=1, the fractional part is coded on 3 bits and programmed by the DIV\_fraction[2:0] bits in the USART\_BRR register, and bit DIV\_fraction[3] must be kept cleared.

*Note:* The baud counters are updated to the new value in the baud registers after a write operation to USART\_BRR. Hence the baud rate register value should not be changed during communication.

**How to derive USARTDIV from USART\_BRR register values when OVER8=0****Example 1:**

If DIV\_Mantissa = 0d27 and DIV\_Fraction = 0d12 (USART\_BRR = 0x1BC), then

Mantissa (USARTDIV) = 0d27

Fraction (USARTDIV) =  $12/16 = 0d0.75$

Therefore USARTDIV = 0d27.75

**Example 2:**

To program USARTDIV = 0d25.62

This leads to:

$DIV\_Fraction = 16 * 0d0.62 = 0d9.92$

The nearest real number is 0d10 = 0xA

$DIV\_Mantissa = \text{mantissa}(0d25.620) = 0d25 = 0x19$

Then, USART\_BRR = 0x19A hence USARTDIV = 0d25.625

**Example 3:**

To program USARTDIV = 0d50.99

This leads to:

$DIV\_Fraction = 16 * 0d0.99 = 0d15.84$

The nearest real number is 0d16 = 0x10 => overflow of DIV\_frac[3:0] => carry must be added up to the mantissa

$DIV\_Mantissa = \text{mantissa}(0d50.990 + \text{carry}) = 0d51 = 0x33$

Then, USART\_BRR = 0x330 hence USARTDIV = 0d51.000

**How to derive USARTDIV from USART\_BRR register values when OVER8=1****Example 1:**

If DIV\_Mantissa = 0x27 and DIV\_Fraction[2:0] = 0d6 (USART\_BRR = 0x1B6), then

Mantissa (USARTDIV) = 0d27

Fraction (USARTDIV) =  $6/8 = 0d0.75$

Therefore USARTDIV = 0d27.75

**Example 2:**

To program USARTDIV = 0d25.62

This leads to:

$DIV\_Fraction = 8 * 0d0.62 = 0d4.96$

The nearest real number is 0d5 = 0x5

$DIV\_Mantissa = \text{mantissa}(0d25.620) = 0d25 = 0x19$



Then, USART\_BRR = 0x195 => USARTDIV = 0d25.625

**Example 3:**

To program USARTDIV = 0d50.99

This leads to:

$$\text{DIV\_Fraction} = 8 \times 0d0.99 = 0d7.92$$

The nearest real number is 0d8 = 0x8 => overflow of the DIV\_frac[2:0] => carry must be added up to the mantissa

$$\text{DIV\_Mantissa} = \text{mantissa} (0d50.990 + \text{carry}) = 0d51 = 0x33$$

Then, USART\_BRR = 0x0330 => USARTDIV = 0d51.000

**Table 74. Error calculation for programmed baud rates at f<sub>PCLK</sub> = 8 MHz or f<sub>PCLK</sub> = 12 MHz, oversampling by 16<sup>(1)</sup>**

Oversampling by 16 (OVER8=0)							
Baud rate <sup>7</sup>		f <sub>PCLK</sub> = 8 MHz			f <sub>PCLK</sub> = 12 MHz		
S.No	Desired	Actual	Value programmed in the baud rate register	% Error = (Calculated - Desired) B.rate / Desired B.rate	Actual	Value programmed in the baud rate register	% Error
1	1.2 Kbps	1.2 Kbps	416.6875	0	1.2 Kbps	625	0
2	2.4 Kbps	2.4 Kbps	208.3125	0.01	2.4 Kbps	312.5	0
3	9.6 Kbps	9.604 Kbps	52.0625	0.04	9.6 Kbps	78.125	0
4	19.2 Kbps	19.185 Kbps	26.0625	0.08	19.2 Kbps	39.0625	0
5	38.4 Kbps	38.462 Kbps	13	0.16	38.339 Kbps	19.5625	0.16
6	57.6 Kbps	57.554 Kbps	8.6875	0.08	57.692 Kbps	13	0.16
7	115.2 Kbps	115.942 Kbps	4.3125	0.64	115.385 Kbps	6.5	0.16
8	230.4 Kbps	228.571 Kbps	2.1875	0.79	230.769 Kbps	3.25	0.16
9	460.8 Kbps	470.588 Kbps	1.0625	2.12	461.538 Kbps	1.625	0.16
10	921.6 Kbps	NA	NA	NA	NA	NA	NA
11	2 MBps	NA	NA	NA	NA	NA	NA
12	3 MBps	NA	NA	NA	NA	NA	NA

1. The lower the CPU clock the lower the accuracy for a particular baud rate. The upper limit of the achievable baud rate can be fixed with these data.



**Table 75. Error calculation for programmed baud rates at  $f_{PCLK} = 8\text{ MHz}$  or  $f_{PCLK} = 12\text{ MHz}$ , oversampling by 8<sup>(1)</sup>**

Oversampling by 8 (OVER8 = 1)							
Baud rate		$f_{PCLK} = 8\text{ MHz}$			$f_{PCLK} = 12\text{ MHz}$		
S.No	Desired	Actual	Value programmed in the baud rate register	% Error = (Calculated - Desired) B.rate / Desired B.rate	Actual	Value programmed in the baud rate register	% Error
1	1.2 KBps	1.2 KBps	833.375	0	1.2 KBps	1250	0
2	2.4 KBps	2.4 KBps	416.625	0.01	2.4 KBps	625	0
3	9.6 KBps	9.604 KBps	104.125	0.04	9.6 KBps	156.25	0
4	19.2 KBps	19.185 KBps	52.125	0.08	19.2 KBps	78.125	0
5	38.4 KBps	38.462 KBps	26	0.16	38.339 KBps	39.125	0.16
6	57.6 KBps	57.554 KBps	17.375	0.08	57.692 KBps	26	0.16
7	115.2 KBps	115.942 KBps	8.625	0.64	115.385 KBps	13	0.16
8	230.4 KBps	228.571 KBps	4.375	0.79	230.769 KBps	6.5	0.16
9	460.8 KBps	470.588 KBps	2.125	2.12	461.538 KBps	3.25	0.16
10	921.6 KBps	888.889 KBps	1.125	3.55	923.077 KBps	1.625	0.16
11	2 MBps	NA	NA	NA	NA	NA	NA
12	3 MBps	NA	NA	NA	NA	NA	NA

1. The lower the CPU clock the lower the accuracy for a particular baud rate. The upper limit of the achievable baud rate can be fixed with these data.

**Table 76. Error calculation for programmed baud rates at  $f_{PCLK} = 16\text{ MHz}$  or  $f_{PCLK} = 24\text{ MHz}$ , oversampling by 16<sup>(1)</sup>**

Oversampling by 16 (OVER8 = 0)							
Baud rate		$f_{PCLK} = 16\text{ MHz}$			$f_{PCLK} = 24\text{ MHz}$		
S.No	Desired	Actual	Value programmed in the baud rate register	% Error = (Calculated - Desired) B.rate / Desired B.rate	Actual	Value programmed in the baud rate register	% Error
1	1.2 KBps	1.2 KBps	833.3125	0	1.2	1250	0
2	2.4 KBps	2.4 KBps	416.6875	0	2.4	625	0
3	9.6 KBps	9.598 KBps	104.1875	0.02	9.6	156.25	0
4	19.2 KBps	19.208 KBps	52.0625	0.04	19.2	78.125	0
5	38.4 KBps	38.369 KBps	26.0625	0.08	38.4	39.0625	0
6	57.6 KBps	57.554 KBps	17.375	0.08	57.554	26.0625	0.08

**Table 76. Error calculation for programmed baud rates at  $f_{PCLK} = 16$  MHz or  $f_{PCLK} = 24$  MHz, oversampling by 16<sup>(1)</sup> (continued)**

Oversampling by 16 (OVER8 = 0)							
Baud rate		$f_{PCLK} = 16$ MHz			$f_{PCLK} = 24$ MHz		
S.No	Desired	Actual	Value programmed in the baud rate register	% Error = (Calculated - Desired) B.rate / Desired B.rate	Actual	Value programmed in the baud rate register	% Error
7	115.2 Kbps	115.108 Kbps	8.6875	0.08	115.385	13	0.16
8	230.4 Kbps	231.884 Kbps	4.3125	0.64	230.769	6.5	0.16
9	460.8 Kbps	457.143 Kbps	2.1875	0.79	461.538	3.25	0.16
10	921.6 Kbps	941.176 Kbps	1.0625	2.12	923.077	1.625	0.16
11	2 MBps	NA	NA	NA	NA	NA	NA
12	3 MBps	NA	NA	NA	NA	NA	NA

1. The lower the CPU clock the lower the accuracy for a particular baud rate. The upper limit of the achievable baud rate can be fixed with these data.

**Table 77. Error calculation for programmed baud rates at  $f_{PCLK} = 16$  MHz or  $f_{PCLK} = 24$  MHz, oversampling by 8<sup>(1)</sup>**

Oversampling by 8 (OVER8=1)							
Baud rate		$f_{PCLK} = 16$ MHz			$f_{PCLK} = 24$ MHz		
S.No	Desired	Actual	Value programmed in the baud rate register	% Error = (Calculated - Desired) B.rate / Desired B.rate	Actual	Value programmed in the baud rate register	% Error
1	1.2 Kbps	1.2 Kbps	1666.625	0	1.2 Kbps	2500	0
2	2.4 Kbps	2.4 Kbps	833.375	0	2.4 Kbps	1250	0
3	9.6 Kbps	9.598 Kbps	208.375	0.02	9.6 Kbps	312.5	0
4	19.2 Kbps	19.208 Kbps	104.125	0.04	19.2 Kbps	156.25	0
5	38.4 Kbps	38.369 Kbps	52.125	0.08	38.4 Kbps	78.125	0
6	57.6 Kbps	57.554 Kbps	34.75	0.08	57.554 Kbps	52.125	0.08
7	115.2 Kbps	115.108 Kbps	17.375	0.08	115.385 Kbps	26	0.16
8	230.4 Kbps	231.884 Kbps	8.625	0.64	230.769 Kbps	13	0.16
9	460.8 Kbps	457.143 Kbps	4.375	0.79	461.538 Kbps	6.5	0.16
10	921.6 Kbps	941.176 Kbps	2.125	2.12	923.077 Kbps	3.25	0.16
11	2 MBps	2000 Kbps	1	0	2000 Kbps	1.5	0
12	3 MBps	NA	NA	NA	3000 Kbps	1	0

1. The lower the CPU clock the lower the accuracy for a particular baud rate. The upper limit of the achievable baud rate can be fixed with these data.

**Table 78. Error calculation for programmed baud rates at  $f_{PCLK} = 8$  MHz or  $f_{PCLK} = 16$  MHz, oversampling by 16<sup>(1)</sup>**

Oversampling by 16 (OVER8=0)							
Baud rate		$f_{PCLK} = 8$ MHz			$f_{PCLK} = 16$ MHz		
S.No	Desired	Actual	Value programmed in the baud rate register	% Error = (Calculated - Desired)B.Rate / Desired B.Rate	Actual	Value programmed in the baud rate register	% Error
1.	2.4 KBps	2.400 KBps	208.3125	0.00%	2.400 KBps	416.6875	0.00%
2.	9.6 KBps	9.604 KBps	52.0625	0.04%	9.598 KBps	104.1875	0.02%
3.	19.2 KBps	19.185 KBps	26.0625	0.08%	19.208 KBps	52.0625	0.04%
4.	57.6 KBps	57.554 KBps	8.6875	0.08%	57.554 KBps	17.3750	0.08%
5.	115.2 KBps	115.942 KBps	4.3125	0.64%	115.108 KBps	8.6875	0.08%
6.	230.4 KBps	228.571 KBps	2.1875	0.79%	231.884 KBps	4.3125	0.64%
7.	460.8 KBps	470.588 KBps	1.0625	2.12%	457.143 KBps	2.1875	0.79%
8.	896 KBps	NA	NA	NA	888.889 KBps	1.1250	0.79%
9.	921.6 KBps	NA	NA	NA	941.176 KBps	1.0625	2.12%
10.	1.792 MBps	NA	NA	NA	NA	NA	NA
11.	1.8432 MBps	NA	NA	NA	NA	NA	NA
12.	3.584 MBps	NA	NA	NA	NA	NA	NA
13.	3.6864 MBps	NA	NA	NA	NA	NA	NA
14.	7.168 MBps	NA	NA	NA	NA	NA	NA
15.	7.3728 MBps	NA	NA	NA	NA	NA	NA

1. The lower the CPU clock the lower the accuracy for a particular baud rate. The upper limit of the achievable baud rate can be fixed with these data.

**Table 79. Error calculation for programmed baud rates at  $f_{PCLK} = 8$  MHz or  $f_{PCLK} = 16$  MHz, oversampling by 8<sup>(1)</sup>**

Oversampling by 8 (OVER8=1)							
Baud rate		$f_{PCLK} = 8$ MHz			$f_{PCLK} = 16$ MHz		
S.No	Desired	Actual	Value programmed in the baud rate register	% Error = (Calculated - Desired)B.Rate / Desired B.Rate	Actual	Value programmed in the baud rate register	% Error
1.	2.4 KBps	2.400 KBps	416.625	0.01%	2.400 KBps	833.375	0.00%
2.	9.6 KBps	9.604 KBps	104.125	0.04%	9.598 KBps	208.375	0.02%
3.	19.2 KBps	19.185 KBps	52.125	0.08%	19.208 KBps	104.125	0.04%

**Table 79. Error calculation for programmed baud rates at  $f_{PCLK} = 8\text{ MHz}$  or  $f_{PCLK} = 16\text{ MHz}$ , oversampling by  $8^{(1)}$  (continued)**

Oversampling by 8 (OVER8=1)							
Baud rate		$f_{PCLK} = 8\text{ MHz}$			$f_{PCLK} = 16\text{ MHz}$		
S.No	Desired	Actual	Value programmed in the baud rate register	% Error = (Calculated - Desired)B.Rate /Desired B.Rate	Actual	Value programmed in the baud rate register	% Error
4.	57.6 KBps	57.557 KBps	17.375	0.08%	57.554 KBps	34.750	0.08%
5.	115.2 KBps	115.942 KBps	8.625	0.64%	115.108 KBps	17.375	0.08%
6.	230.4 KBps	228.571 KBps	4.375	0.79%	231.884 KBps	8.625	0.64%
7.	460.8 KBps	470.588 KBps	2.125	2.12%	457.143 KBps	4.375	0.79%
8.	896 KBps	888.889 KBps	1.125	0.79%	888.889 KBps	2.250	0.79%
9.	921.6 KBps	888.889 KBps	1.125	3.55%	941.176 KBps	2.125	2.12%
10.	1.792 MBps	NA	NA	NA	1.7777 MBps	1.125	0.79%
11.	1.8432 MBps	NA	NA	NA	1.7777 MBps	1.125	3.55%
12.	3.584 MBps	NA	NA	NA	NA	NA	NA
13.	3.6864 MBps	NA	NA	NA	NA	NA	NA
14.	7.168 MBps	NA	NA	NA	NA	NA	NA
15.	7.3728 MBps	NA	NA	NA	NA	NA	NA

1. The lower the CPU clock the lower the accuracy for a particular baud rate. The upper limit of the achievable baud rate can be fixed with these data.

**Table 80. Error calculation for programmed baud rates at  $f_{PCLK} = 30\text{ MHz}$  or  $f_{PCLK} = 60\text{ MHz}$ , oversampling by  $16^{(1)(2)}$**

Oversampling by 16 (OVER8=0)							
Baud rate		$f_{PCLK} = 30\text{ MHz}$			$f_{PCLK} = 60\text{ MHz}$		
S.No	Desired	Actual	Value programmed in the baud rate register	% Error = (Calculated - Desired)B.Rate /Desired B.Rate	Actual	Value programmed in the baud rate register	% Error
1.	2.4 KBps	2.400 KBps	781.2500	0.00%	2.400 KBps	1562.5000	0.00%
2.	9.6 KBps	9.600 KBps	195.3125	0.00%	9.600 KBps	390.6250	0.00%
3.	19.2 KBps	19.194 KBps	97.6875	0.03%	19.200 KBps	195.3125	0.00%
4.	57.6 KBps	57.582KBps	32.5625	0.03%	57.582 KBps	65.1250	0.03%
5.	115.2 KBps	115.385 KBps	16.2500	0.16%	115.163 KBps	32.5625	0.03%
6.	230.4 KBps	230.769 KBps	8.1250	0.16%	230.769KBps	16.2500	0.16%
7.	460.8 KBps	461.538 KBps	4.0625	0.16%	461.538 KBps	8.1250	0.16%

**Table 80. Error calculation for programmed baud rates at  $f_{PCLK} = 30\text{ MHz}$  or  $f_{PCLK} = 60\text{ MHz}$ , oversampling by  $16^{(1)(2)}$  (continued)**

Oversampling by 16 (OVER8=0)							
Baud rate		$f_{PCLK} = 30\text{ MHz}$			$f_{PCLK} = 60\text{ MHz}$		
S.No	Desired	Actual	Value programmed in the baud rate register	% Error = $\frac{\text{Calculated} - \text{Desired}}{\text{Desired}} \times 100\%$	Actual	Value programmed in the baud rate register	% Error
8.	896 KBps	909.091 KBps	2.0625	1.46%	895.522 KBps	4.1875	0.05%
9.	921.6 KBps	909.091 KBps	2.0625	1.36%	923.077 KBps	4.0625	0.16%
10.	1.792 MBps	1.1764 MBps	1.0625	1.52%	1.8182 MBps	2.0625	1.36%
11.	1.8432 MBps	1.8750 MBps	1.0000	1.73%	1.8182 MBps	2.0625	1.52%
12.	3.584 MBps	NA	NA	NA	3.2594 MBps	1.0625	1.52%
13.	3.6864 MBps	NA	NA	NA	3.7500 MBps	1.0000	1.73%
14.	7.168 MBps	NA	NA	NA	NA	NA	NA
15.	7.3728 MBps	NA	NA	NA	NA	NA	NA

1. The lower the CPU clock the lower the accuracy for a particular baud rate. The upper limit of the achievable baud rate can be fixed with these data.
2. Only USART1 and USART6 are clocked with PCLK2. Other USARTs are clocked with PCLK1. Refer to the device datasheets for the maximum values for PCLK1 and PCLK2.

**Table 81. Error calculation for programmed baud rates at  $f_{PCLK} = 30\text{ MHz}$  or  $f_{PCLK} = 60\text{ MHz}$ , oversampling by  $8^{(1)(2)}$**

Oversampling by 8 (OVER8=1)							
Baud rate		$f_{PCLK} = 30\text{ MHz}$			$f_{PCLK} = 60\text{ MHz}$		
S.No	Desired	Actual	Value programmed in the baud rate register	% Error = $\frac{\text{Calculated} - \text{Desired}}{\text{Desired}} \times 100\%$	Actual	Value programmed in the baud rate register	% Error
1.	2.4 KBps	2.400 KBps	1562.5000	0.00%	2.400 KBps	3125.0000	0.00%
2.	9.6 KBps	9.600 KBps	390.6250	0.00%	9.600 KBps	781.2500	0.00%
3.	19.2 KBps	19.194 KBps	195.3750	0.03%	19.200 KBps	390.6250	0.00%
4.	57.6 KBps	57.582 KBps	65.1250	0.16%	57.582 KBps	130.2500	0.03%
5.	115.2 KBps	115.385 KBps	32.5000	0.16%	115.163 KBps	65.1250	0.03%
6.	230.4 KBps	230.769 KBps	16.2500	0.16%	230.769 KBps	32.5000	0.16%
7.	460.8 KBps	461.538 KBps	8.1250	0.16%	461.538 KBps	16.2500	0.16%
8.	896 KBps	909.091 KBps	4.1250	1.46%	895.522 KBps	8.3750	0.05%

**Table 81. Error calculation for programmed baud rates at  $f_{PCLK} = 30$  MHz or  $f_{PCLK} = 60$  MHz, oversampling by  $8^{(1)(2)}$  (continued)**

Oversampling by 8 (OVER8=1)							
Baud rate		$f_{PCLK} = 30$ MHz			$f_{PCLK} = 60$ MHz		
S.No	Desired	Actual	Value programmed in the baud rate register	% Error = (Calculated - Desired)B.Rate /Desired B.Rate	Actual	Value programmed in the baud rate register	% Error
9.	921.6 KBps	909.091 KBps	4.1250	1.36%	923.077 KBps	8.1250	0.16%
10.	1.792 MBps	1.7647 MBps	2.1250	1.52%	1.8182 MBps	4.1250	1.46%
11.	1.8432 MBps	1.8750 MBps	2.0000	1.73%	1.8182 MBps	4.1250	1.36%
12.	3.584 MBps	3.7500 MBps	1.0000	4.63%	3.5294 MBps	2.1250	1.52%
13.	3.6864 MBps	3.7500 MBps	1.0000	1.73%	3.7500 MBps	2.0000	1.73%
14.	7.168 MBps	NA	NA	NA	7.5000 MBps	1.0000	4.63%
15.	7.3728 MBps	NA	NA	NA	7.5000 MBps	1.0000	1.73%

1. The lower the CPU clock the lower the accuracy for a particular baud rate. The upper limit of the achievable baud rate can be fixed with these data.
2. Only USART1 and USART6 are clocked with PCLK2. Other USARTs are clocked with PCLK1. Refer to the device datasheets for the maximum values for PCLK1 and PCLK2.

**Table 82. Error calculation for programmed baud rates at  $f_{PCLK} = 42$  MHz or  $f_{PCLK} = 84$  Hz, oversampling by  $16^{(1)(2)}$**

Oversampling by 16 (OVER8=0)							
Baud rate		$f_{PCLK} = 42$ MHz			$f_{PCLK} = 84$ MHz		
S.No	Desired	Actual	Value programmed in the baud rate register	% Error = (Calculated - Desired)B.Rate /Desired B.Rate	Actual	Value programmed in the baud rate register	% Error
1	1.2 KBps	1.2 KBps	2187.5	0	1.2 KBps	4375	0
2	2.4 KBps	2.4 KBps	1093.75	0	2.4 KBps	2187.5	0
3	9.6 KBps	9.6 KBps	273.4375	0	9.6 KBps	546.875	0
4	19.2 KBps	19.195 KBps	136.75	0.02	19.2 KBps	273.4375	0
5	38.4 KBps	38.391 KBps	68.375	0.02	38.391 KBps	136.75	0.02
6	57.6 KBps	57.613 KBps	45.5625	0.02	57.613 KBps	91.125	0.02
7	115.2 KBps	115.068 KBps	22.8125	0.11	115.226 KBps	45.5625	0.02
8	230.4 KBps	230.769 KBps	11.375	0.16	230.137 KBps	22.8125	0.11
9	460.8 KBps	461.538 KBps	5.6875	0.16	461.538 KBps	11.375	0.16
10	921.6 KBps	913.043 KBps	2.875	0.93	923.076 KBps	5.6875	0.93

**Table 82. Error calculation for programmed baud rates at  $f_{PCLK} = 42$  MHz or  $f_{PCLK} = 84$  Hz, oversampling by  $16^{(1)(2)}$  (continued)**

Oversampling by 16 (OVER8=0)							
Baud rate		$f_{PCLK} = 42$ MHz			$f_{PCLK} = 84$ MHz		
S.No	Desired	Actual	Value programmed in the baud rate register	% Error = $\frac{\text{Calculated} - \text{Desired}}{\text{Desired}} \times 100$	Actual	Value programmed in the baud rate register	% Error
11	1.792 MBps	1.826 MBps	1.4375	1.9	1.787 MBps	2.9375	0.27
12	1.8432 MBps	1.826 MBps	1.4375	0.93	1.826 MBps	2.875	0.93
13	3.584 MBps	N.A	N.A	N.A	3.652 MBps	1.4375	1.9
14	3.6864 MBps	N.A	N.A	N.A	3.652 MBps	1.4375	0.93
15	7.168 MBps	N.A	N.A	N.A	N.A	N.A	N.A
16	7.3728 MBps	N.A	N.A	N.A	N.A	N.A	N.A
18	9 MBps	N.A	N.A	N.A	N.A	N.A	N.A
20	10.5 MBps	N.A	N.A	N.A	N.A	N.A	N.A

1. The lower the CPU clock the lower the accuracy for a particular baud rate. The upper limit of the achievable baud rate can be fixed with these data.
2. Only USART1 and USART6 are clocked with PCLK2. Other USARTs are clocked with PCLK1. Refer to the device datasheets for the maximum values for PCLK1 and PCLK2.

**Table 83. Error calculation for programmed baud rates at  $f_{PCLK} = 42$  MHz or  $f_{PCLK} = 84$  MHz, oversampling by  $8^{(1)(2)}$**

Oversampling by 8 (OVER8=1)							
Baud rate		$f_{PCLK} = 42$ MHz			$f_{PCLK} = 84$ MHz		
S.No	Desired	Actual	Value programmed in the baud rate register	% Error = $\frac{\text{Calculated} - \text{Desired}}{\text{Desired}} \times 100$	Actual	Value programmed in the baud rate register	% Error
1.	1.2 KBps	1.2 KBps	4375	0	1.2 KBps	8750	0
2.	2.4 KBps	2.4 KBps	2187.5	0	2.4 KBps	4375	0
3.	9.6 KBps	9.6 KBps	546.875	0	9.6 KBps	1093.75	0
4.	19.2 KBps	19.195 KBps	273.5	0.02	19.2 KBps	546.875	0
5.	38.4 KBps	38.391 KBps	136.75	0.02	38.391 KBps	273.5	0.02
6.	57.6 KBps	57.613 KBps	91.125	0.02	57.613 KBps	182.25	0.02
7.	115.2 KBps	115.068 KBps	45.625	0.11	115.226 KBps	91.125	0.02
8.	230.4 KBps	230.769 KBps	22.75	0.11	230.137 KBps	45.625	0.11





**Table 83. Error calculation for programmed baud rates at  $f_{PCLK} = 42$  MHz or  $f_{PCLK} = 84$  MHz, oversampling by  $8^{(1)(2)}$  (continued)**

Oversampling by 8 (OVER8=1)							
Baud rate		$f_{PCLK} = 42$ MHz			$f_{PCLK} = 84$ MHz		
S.No	Desired	Actual	Value programmed in the baud rate register	% Error = $\frac{\text{Calculated} - \text{Desired}}{\text{Desired}} \times 100$	Actual	Value programmed in the baud rate register	% Error
9.	460.8 KBps	461.538 KBps	11.375	0.16	461.538 KBps	22.75	0.16
10.	921.6 KBps	913.043 KBps	5.75	0.93	923.076 KBps	11.375	0.93
11.	1.792 MBps	1.826 MBps	2.875	1.9	1.787Mbps	5.875	0.27
12.	1.8432 MBps	1.826 MBps	2.875	0.93	1.826 MBps	5.75	0.93
13.	3.584 MBps	3.5 MBps	1.5	2.34	3.652 MBps	2.875	1.9
14.	3.6864 MBps	3.82 MBps	1.375	3.57	3.652 MBps	2.875	0.93
15.	7.168 MBps	N.A	N.A	N.A	7 MBps	1.5	2.34
16.	7.3728 MBps	N.A	N.A	N.A	7.636 MBps	1.375	3.57
18.	9 MBps	N.A	N.A	N.A	9.333 MBps	1.125	3.7
20.	10.5 MBps	N.A	N.A	N.A	10.5 MBps	1	0

1. The lower the CPU clock the lower the accuracy for a particular baud rate. The upper limit of the achievable baud rate can be fixed with these data.
2. Only USART1 and USART6 are clocked with PCLK2. Other USARTs are clocked with PCLK1. Refer to the device datasheets for the maximum values for PCLK1 and PCLK2.

### 19.3.5 USART receiver tolerance to clock deviation

The USART asynchronous receiver works correctly only if the total clock system deviation is smaller than the USART receiver’s tolerance. The causes which contribute to the total deviation are:

- DTRA: Deviation due to the transmitter error (which also includes the deviation of the transmitter’s local oscillator)
- DQUANT: Error due to the baud rate quantization of the receiver
- DREC: Deviation of the receiver’s local oscillator
- DTCL: Deviation due to the transmission line (generally due to the transceivers which can introduce an asymmetry between the low-to-high transition timing and the high-to-low transition timing)

$$DTRA + DQUANT + DREC + DTCL < \text{USART receiver’s tolerance}$$

The USART receiver’s tolerance to properly receive data is equal to the maximum tolerated deviation and depends on the following choices:

- 10- or 11-bit character length defined by the M bit in the USART\_CR1 register
- oversampling by 8 or 16 defined by the OVER8 bit in the USART\_CR1 register
- use of fractional baud rate or not
- use of 1 bit or 3 bits to sample the data, depending on the value of the ONEBIT bit in the USART\_CR3 register

**Table 84. USART receiver’s tolerance when DIV fraction is 0**

M bit	OVER8 bit = 0		OVER8 bit = 1	
	ONEBIT=0	ONEBIT=1	ONEBIT=0	ONEBIT=1
0	3.75%	4.375%	2.50%	3.75%
1	3.41%	3.97%	2.27%	3.41%

**Table 85. USART receiver tolerance when DIV\_Fraction is different from 0**

M bit	OVER8 bit = 0		OVER8 bit = 1	
	ONEBIT=0	ONEBIT=1	ONEBIT=0	ONEBIT=1
0	3.33%	3.88%	2%	3%
1	3.03%	3.53%	1.82%	2.73%

*Note:* The figures specified in [Table 84](#) and [Table 85](#) may slightly differ in the special case when the received frames contain some Idle frames of exactly 10-bit times when M=0 (11-bit times when M=1).

### 19.3.6 Multiprocessor communication

There is a possibility of performing multiprocessor communication with the USART (several USARTs connected in a network). For instance one of the USARTs can be the master, its TX output is connected to the RX input of the other USART. The others are slaves, their respective TX outputs are logically ANDed together and connected to the RX input of the master.

In multiprocessor configurations it is often desirable that only the intended message recipient should actively receive the full message contents, thus reducing redundant USART service overhead for all non addressed receivers.

The non addressed devices may be placed in mute mode by means of the muting function. In mute mode:

- None of the reception status bits can be set.
- All the receive interrupts are inhibited.
- The RWU bit in USART\_CR1 register is set to 1. RWU can be controlled automatically by hardware or written by the software under certain conditions.

The USART can enter or exit from mute mode using one of two methods, depending on the WAKE bit in the USART\_CR1 register:

- Idle Line detection if the WAKE bit is reset,
- Address Mark detection if the WAKE bit is set.

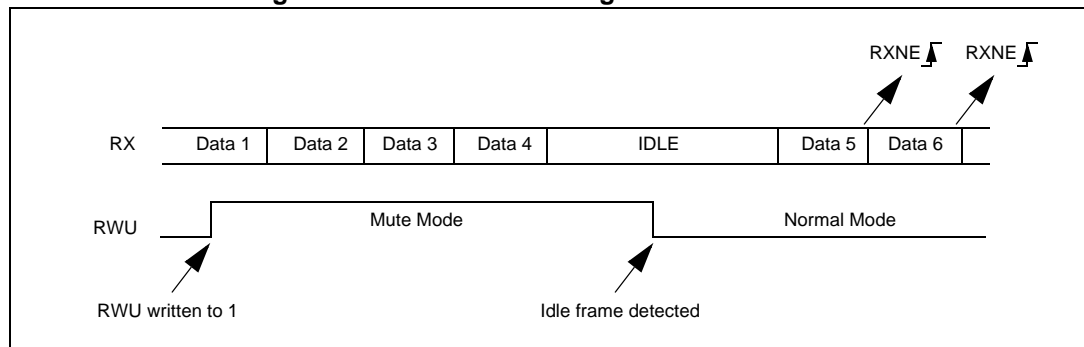
**Idle line detection (WAKE=0)**

The USART enters mute mode when the RWU bit is written to 1.

It wakes up when an Idle frame is detected. Then the RWU bit is cleared by hardware but the IDLE bit is not set in the USART\_SR register. RWU can also be written to 0 by software.

An example of mute mode behavior using Idle line detection is given in *Figure 174*.

**Figure 174. Mute mode using Idle line detection**



**Address mark detection (WAKE=1)**

In this mode, bytes are recognized as addresses if their MSB is a '1' else they are considered as data. In an address byte, the address of the targeted receiver is put on the 4 LSB. This 4-bit word is compared by the receiver with its own address which is programmed in the ADD bits in the USART\_CR2 register.

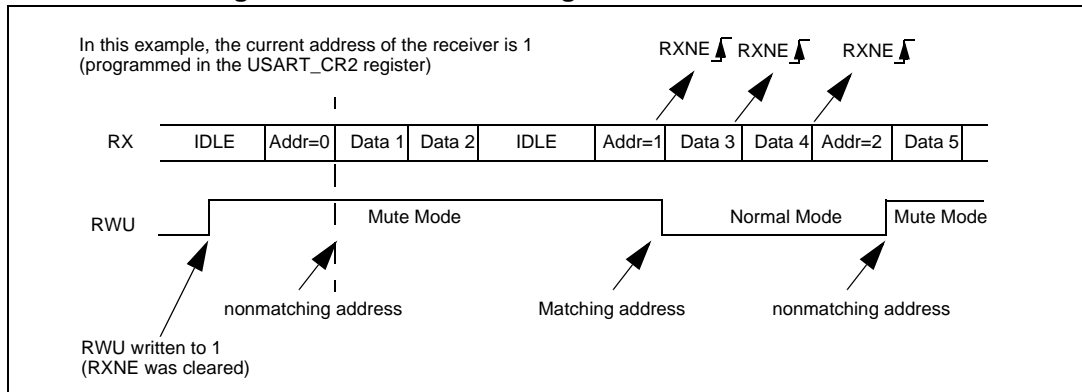
The USART enters mute mode when an address character is received which does not match its programmed address. In this case, the RWU bit is set by hardware. The RXNE flag is not set for this address byte and no interrupt nor DMA request is issued as the USART would have entered mute mode.

It exits from mute mode when an address character is received which matches the programmed address. Then the RWU bit is cleared and subsequent bytes are received normally. The RXNE bit is set for the address character since the RWU bit has been cleared.

The RWU bit can be written to as 0 or 1 when the receiver buffer contains no data (RXNE=0 in the USART\_SR register). Otherwise the write attempt is ignored.

An example of mute mode behavior using address mark detection is given in *Figure 175*.

Figure 175. Mute mode using address mark detection



### 19.3.7 Parity control

Parity control (generation of parity bit in transmission and parity checking in reception) can be enabled by setting the PCE bit in the USART\_CR1 register. Depending on the frame length defined by the M bit, the possible USART frame formats are as listed in [Table 86](#).

Table 86. Frame formats

M bit	PCE bit	USART frame <sup>(1)</sup>
0	0	SB   8 bit data   STB
0	1	SB   7-bit data   PB   STB
1	0	SB   9-bit data   STB
1	1	SB   8-bit data PB   STB

1. Legends: SB: start bit, STB: stop bit, PB: parity bit.

#### Even parity

The parity bit is calculated to obtain an even number of “1s” inside the frame made of the 7 or 8 LSB bits (depending on whether M is equal to 0 or 1) and the parity bit.

E.g.: data=00110101; 4 bits set => parity bit will be 0 if even parity is selected (PS bit in USART\_CR1 = 0).

#### Odd parity

The parity bit is calculated to obtain an odd number of “1s” inside the frame made of the 7 or 8 LSB bits (depending on whether M is equal to 0 or 1) and the parity bit.

E.g.: data=00110101; 4 bits set => parity bit will be 1 if odd parity is selected (PS bit in USART\_CR1 = 1).

#### Parity checking in reception

If the parity check fails, the PE flag is set in the USART\_SR register and an interrupt is generated if PEIE is set in the USART\_CR1 register. The PE flag is cleared by a software sequence (a read from the status register followed by a read or write access to the USART\_DR data register).

*Note:* In case of wakeup by an address mark: the MSB bit of the data is taken into account to identify an address but not the parity bit. And the receiver does not check the parity of the address data (PE is not set in case of a parity error).

### Parity generation in transmission

If the PCE bit is set in USART\_CR1, then the MSB bit of the data written in the data register is transmitted but is changed by the parity bit (even number of “1s” if even parity is selected (PS=0) or an odd number of “1s” if odd parity is selected (PS=1)).

*Note:* The software routine that manages the transmission can activate the software sequence which clears the PE flag (a read from the status register followed by a read or write access to the data register). When operating in half-duplex mode, depending on the software, this can cause the PE flag to be unexpectedly cleared.

## 19.3.8 LIN (local interconnection network) mode

The LIN mode is selected by setting the LINEN bit in the USART\_CR2 register. In LIN mode, the following bits must be kept cleared:

- STOP[1:0] and CLKEN in the USART\_CR2 register
- SCEN, HDSEL and IREN in the USART\_CR3 register.

### LIN transmission

The same procedure explained in [Section 19.3.2](#) has to be applied for LIN Master transmission than for normal USART transmission with the following differences:

- Clear the M bit to configure 8-bit word length.
- Set the LINEN bit to enter LIN mode. In this case, setting the SBK bit sends 13 ‘0 bits as a break character. Then a bit of value ‘1 is sent to allow the next start detection.

### LIN reception

A break detection circuit is implemented on the USART interface. The detection is totally independent from the normal USART receiver. A break can be detected whenever it occurs, during Idle state or during a frame.

When the receiver is enabled (RE=1 in USART\_CR1), the circuit looks at the RX input for a start signal. The method for detecting start bits is the same when searching break characters or data. After a start bit has been detected, the circuit samples the next bits exactly like for the data (on the 8th, 9th and 10th samples). If 10 (when the LBDL = 0 in USART\_CR2) or 11 (when LBDL=1 in USART\_CR2) consecutive bits are detected as ‘0, and are followed by a delimiter character, the LBD flag is set in USART\_SR. If the LBDIE bit=1, an interrupt is generated. Before validating the break, the delimiter is checked for as it signifies that the RX line has returned to a high level.

If a ‘1 is sampled before the 10 or 11 have occurred, the break detection circuit cancels the current detection and searches for a start bit again.

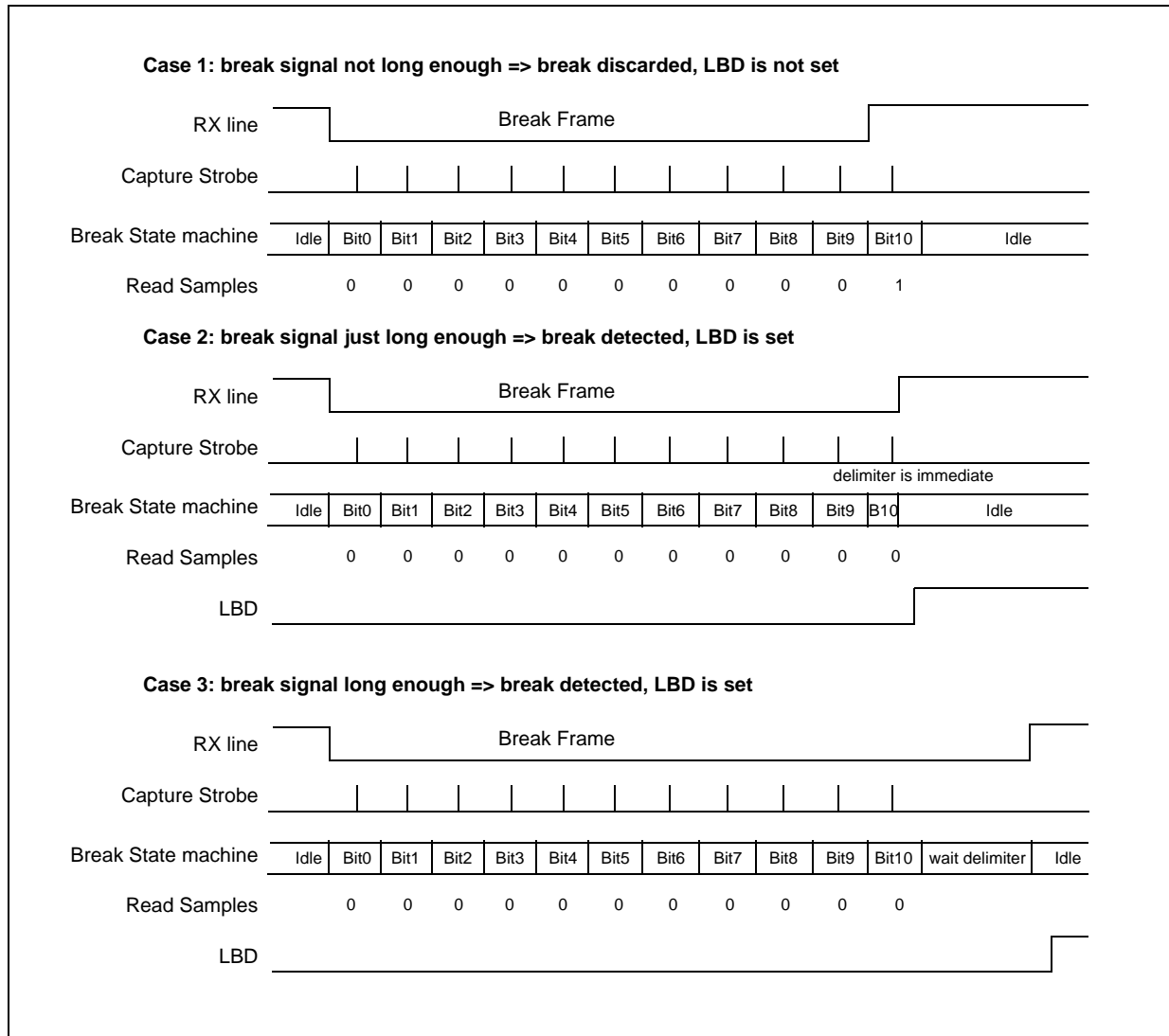
If the LIN mode is disabled (LINEN=0), the receiver continues working as normal USART, without taking into account the break detection.

If the LIN mode is enabled (LINEN=1), as soon as a framing error occurs (i.e. stop bit detected at ‘0, which will be the case for any break frame), the receiver stops until the break detection circuit receives either a ‘1, if the break word was not complete, or a delimiter character if a break has been detected.

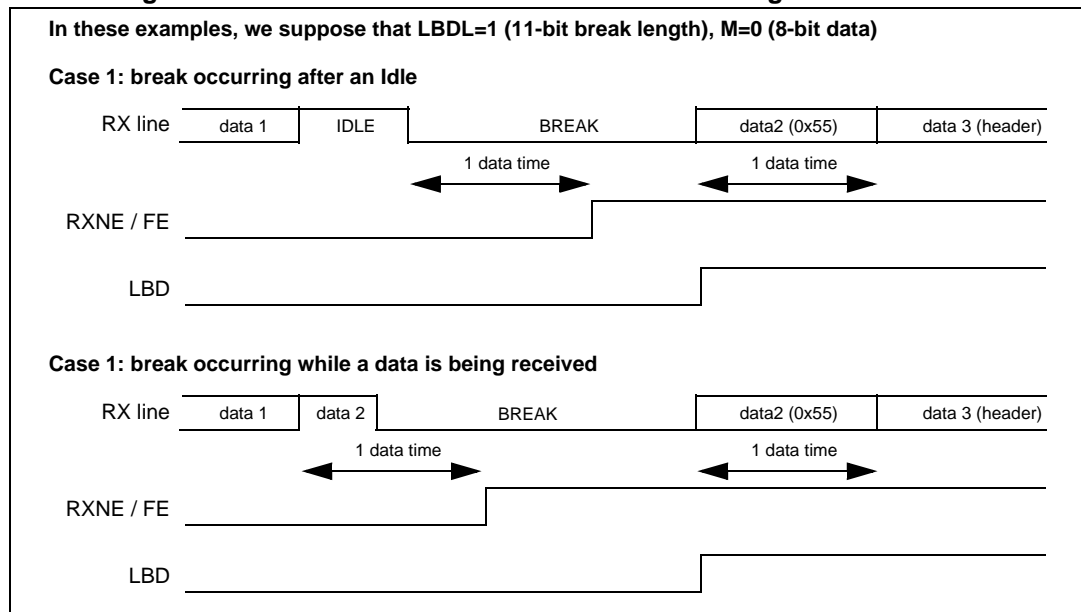
The behavior of the break detector state machine and the break flag is shown on the [Figure 176: Break detection in LIN mode \(11-bit break length - LBDL bit is set\)](#) on page 529.

Examples of break frames are given on [Figure 177: Break detection in LIN mode vs. Framing error detection](#) on page 530.

**Figure 176. Break detection in LIN mode (11-bit break length - LBDL bit is set)**



**Figure 177. Break detection in LIN mode vs. Framing error detection**



### 19.3.9 USART synchronous mode

The synchronous mode is selected by writing the CLKEN bit in the USART\_CR2 register to 1. In synchronous mode, the following bits must be kept cleared:

- LINEN bit in the USART\_CR2 register,
- SCEN, HDSEL and IREN bits in the USART\_CR3 register.

The USART allows the user to control a bidirectional synchronous serial communications in master mode. The SCLK pin is the output of the USART transmitter clock. No clock pulses are sent to the SCLK pin during start bit and stop bit. Depending on the state of the LBCL bit in the USART\_CR2 register clock pulses will or will not be generated during the last valid data bit (address mark). The CPOL bit in the USART\_CR2 register allows the user to select the clock polarity, and the CPHA bit in the USART\_CR2 register allows the user to select the phase of the external clock (see [Figure 178](#), [Figure 179](#) & [Figure 180](#)).

During the Idle state, preamble and send break, the external SCLK clock is not activated.

In synchronous mode the USART transmitter works exactly like in asynchronous mode. But as SCLK is synchronized with TX (according to CPOL and CPHA), the data on TX is synchronous.

In this mode the USART receiver works in a different manner compared to the asynchronous mode. If RE=1, the data is sampled on SCLK (rising or falling edge, depending on CPOL and CPHA), without any oversampling. A setup and a hold time must be respected (which depends on the baud rate: 1/16 bit time).

*Note:* The SCLK pin works in conjunction with the TX pin. Thus, the clock is provided only if the transmitter is enabled (TE=1) and a data is being transmitted (the data register USART\_DR

has been written). This means that it is not possible to receive a synchronous data without transmitting data.

The LBCL, CPOL and CPHA bits have to be selected when both the transmitter and the receiver are disabled ( $TE=RE=0$ ) to ensure that the clock pulses function correctly. These bits should not be changed while the transmitter or the receiver is enabled.

It is advised that TE and RE are set in the same instruction in order to minimize the setup and the hold time of the receiver.

The USART supports master mode only: it cannot receive or send data related to an input clock (SCLK is always an output).

Figure 178. USART example of synchronous transmission

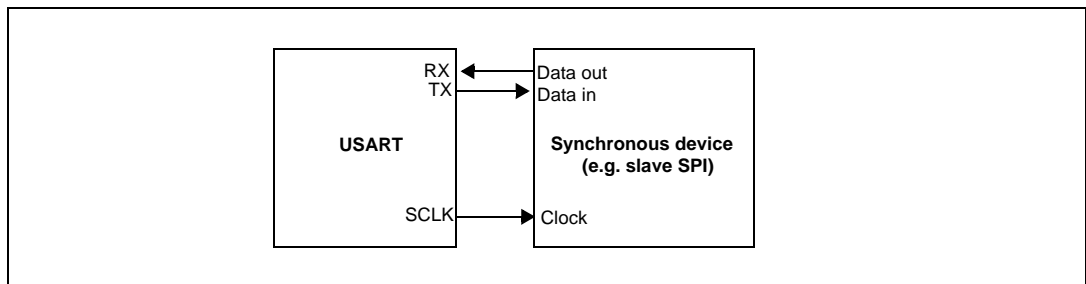
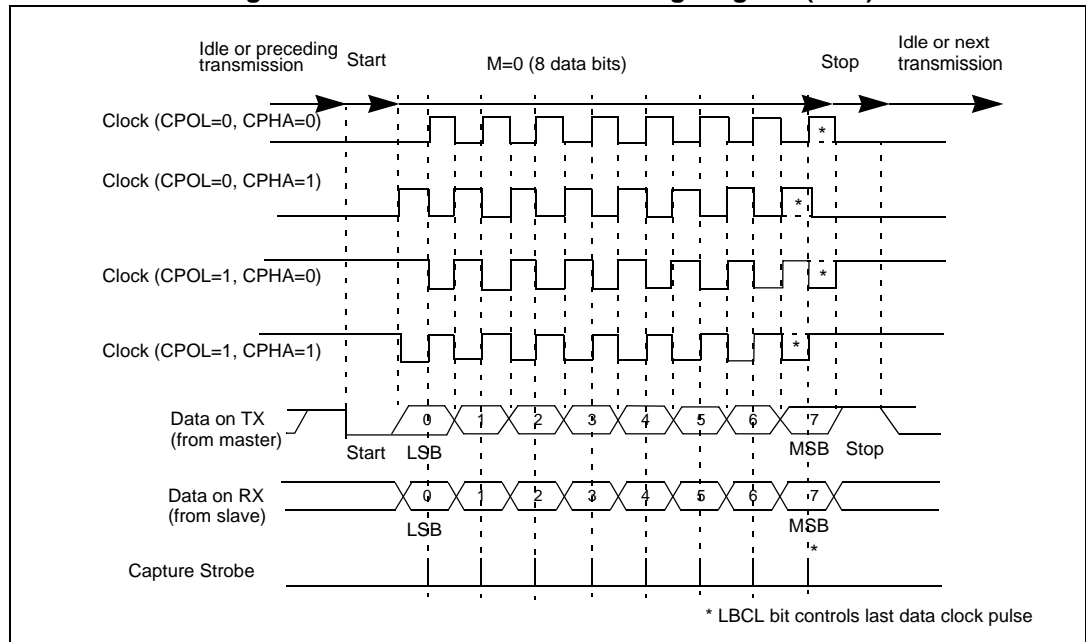
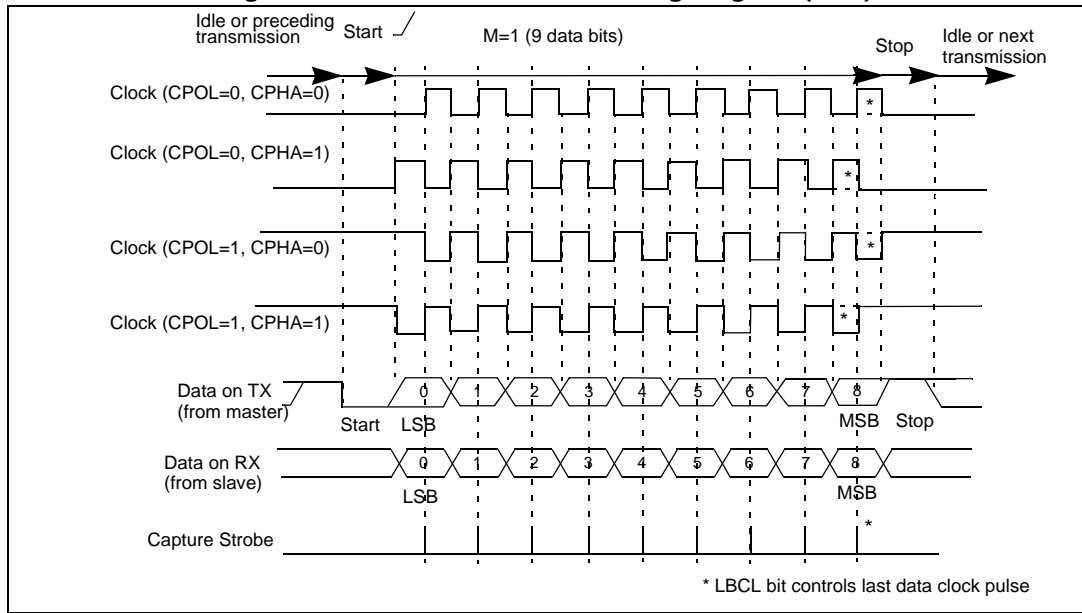


Figure 179. USART data clock timing diagram (M=0)

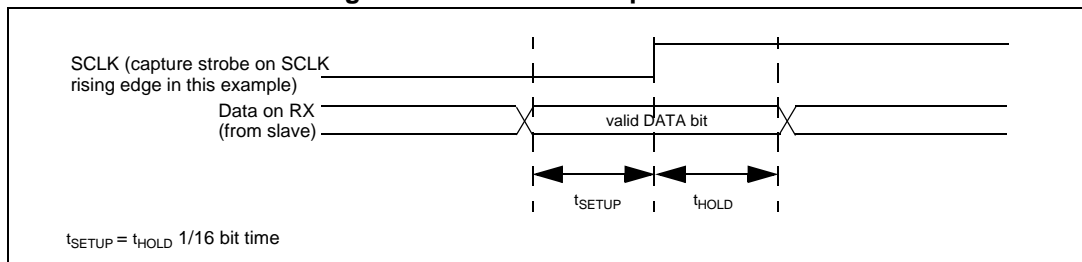




**Figure 180. USART data clock timing diagram (M=1)**



**Figure 181. RX data setup/hold time**



*Note:* The function of SCLK is different in Smartcard mode. Refer to the Smartcard mode chapter for more details.

### 19.3.10 Single-wire half-duplex communication

The single-wire half-duplex mode is selected by setting the HDSEL bit in the USART\_CR3 register. In this mode, the following bits must be kept cleared:

- LINEN and CLKEN bits in the USART\_CR2 register,
- SCEN and IREN bits in the USART\_CR3 register.

The USART can be configured to follow a single-wire half-duplex protocol where the TX and RX lines are internally connected. The selection between half- and full-duplex communication is made with a control bit 'HALF DUPLEX SEL' (HDSEL in USART\_CR3).

As soon as HDSEL is written to 1:

- the TX and RX lines are internally connected
- the RX pin is no longer used
- the TX pin is always released when no data is transmitted. Thus, it acts as a standard I/O in idle or in reception. It means that the I/O must be configured so that TX is configured as floating input (or output high open-drain) when not driven by the USART.

Apart from this, the communications are similar to what is done in normal USART mode. The conflicts on the line must be managed by the software (by the use of a centralized arbiter, for instance). In particular, the transmission is never blocked by hardware and continue to occur as soon as a data is written in the data register while the TE bit is set.

### 19.3.11 Smartcard

The Smartcard mode is selected by setting the SCEN bit in the USART\_CR3 register. In smartcard mode, the following bits must be kept cleared:

- LINEN bit in the USART\_CR2 register,
- HDSEL and IREN bits in the USART\_CR3 register.

Moreover, the CLKEN bit may be set in order to provide a clock to the smartcard.

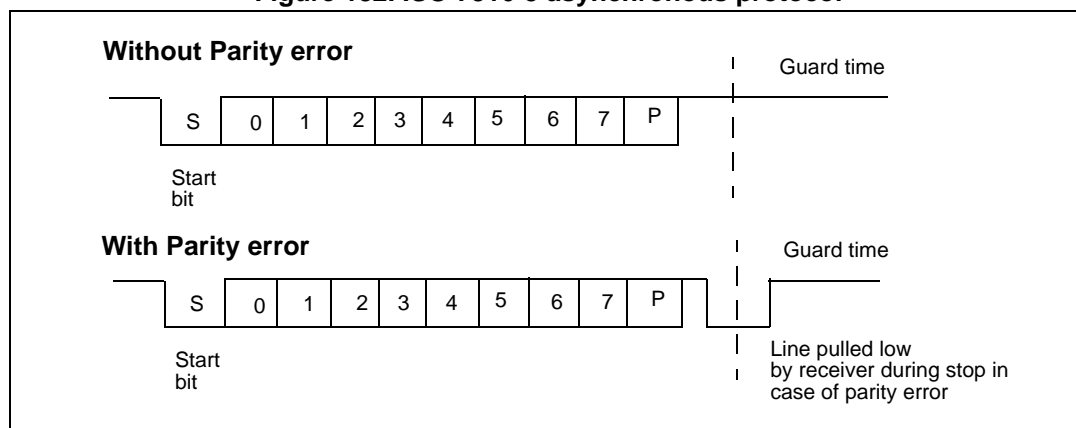
The Smartcard interface is designed to support asynchronous protocol Smartcards as defined in the ISO 7816-3 standard. The USART should be configured as:

- 8 bits plus parity: where M=1 and PCE=1 in the USART\_CR1 register
- 1.5 stop bits when transmitting and receiving: where STOP=11 in the USART\_CR2 register.

*Note:* It is also possible to choose 0.5 stop bit for receiving but it is recommended to use 1.5 stop bits for both transmitting and receiving to avoid switching between the two configurations.

Figure 182 shows examples of what can be seen on the data line with and without parity error.

Figure 182. ISO 7816-3 asynchronous protocol



When connected to a Smartcard, the TX output of the USART drives a bidirectional line that is also driven by the Smartcard. The TX pin must be configured as open-drain.

Smartcard is a single wire half duplex communication protocol.

- Transmission of data from the transmit shift register is guaranteed to be delayed by a minimum of 1/2 baud clock. In normal operation a full transmit shift register will start shifting on the next baud clock edge. In Smartcard mode this transmission is further delayed by a guaranteed 1/2 baud clock.
- If a parity error is detected during reception of a frame programmed with a 0.5 or 1.5 stop bit period, the transmit line is pulled low for a baud clock period after the completion of the receive frame. This is to indicate to the Smartcard that the data transmitted to USART has not been correctly received. This NACK signal (pulling transmit line low for 1 baud clock) will cause a framing error on the transmitter side

(configured with 1.5 stop bits). The application can handle re-sending of data according to the protocol. A parity error is 'NACK'ed by the receiver if the NACK control bit is set, otherwise a NACK is not transmitted.

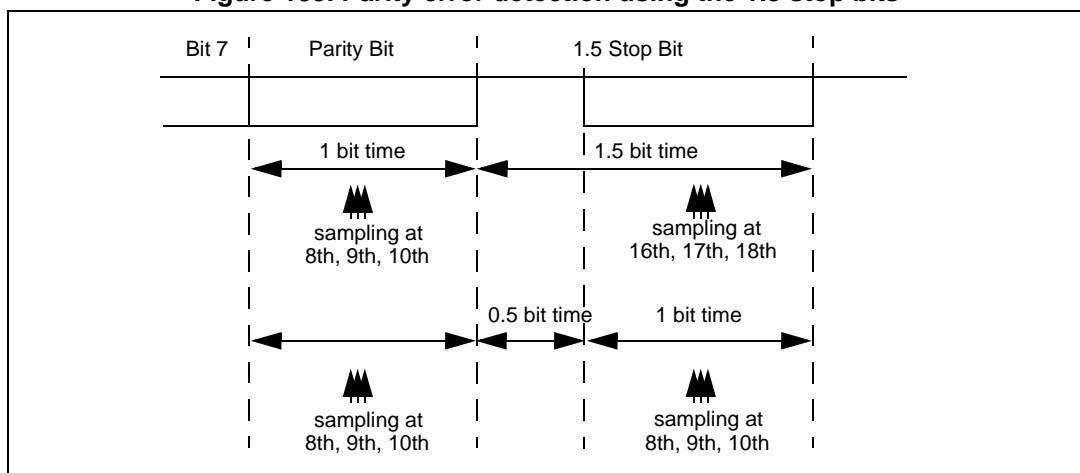
- The assertion of the TC flag can be delayed by programming the Guard Time register. In normal operation, TC is asserted when the transmit shift register is empty and no further transmit requests are outstanding. In Smartcard mode an empty transmit shift register triggers the guard time counter to count up to the programmed value in the Guard Time register. TC is forced low during this time. When the guard time counter reaches the programmed value TC is asserted high.
- The de-assertion of TC flag is unaffected by Smartcard mode.
- If a framing error is detected on the transmitter end (due to a NACK from the receiver), the NACK will not be detected as a start bit by the receive block of the transmitter. According to the ISO protocol, the duration of the received NACK can be 1 or 2 baud clock periods.
- On the receiver side, if a parity error is detected and a NACK is transmitted the receiver will not detect the NACK as a start bit.

*Note: A break character is not significant in Smartcard mode. A 0x00 data with a framing error will be treated as data and not as a break.*

*No Idle frame is transmitted when toggling the TE bit. The Idle frame (as defined for the other configurations) is not defined by the ISO protocol.*

Figure 183 details how the NACK signal is sampled by the USART. In this example the USART is transmitting a data and is configured with 1.5 stop bits. The receiver part of the USART is enabled in order to check the integrity of the data and the NACK signal.

**Figure 183. Parity error detection using the 1.5 stop bits**



The USART can provide a clock to the smartcard through the SCLK output. In smartcard mode, SCLK is not associated to the communication but is simply derived from the internal peripheral input clock through a 5-bit prescaler. The division ratio is configured in the prescaler register USART\_GTPR. SCLK frequency can be programmed from  $f_{CK}/2$  to  $f_{CK}/62$ , where  $f_{CK}$  is the peripheral input clock.

### 19.3.12 IrDA SIR ENDEC block

The IrDA mode is selected by setting the IREN bit in the USART\_CR3 register. In IrDA mode, the following bits must be kept cleared:

- LINEN, STOP and CLKEN bits in the USART\_CR2 register,
- SCEN and HDSEL bits in the USART\_CR3 register.

The IrDA SIR physical layer specifies use of a Return to Zero, Inverted (RZI) modulation scheme that represents logic 0 as an infrared light pulse (see [Figure 184](#)).

The SIR Transmit encoder modulates the Non Return to Zero (NRZ) transmit bit stream output from USART. The output pulse stream is transmitted to an external output driver and infrared LED. USART supports only bit rates up to 115.2Kbps for the SIR ENDEC. In normal mode the transmitted pulse width is specified as 3/16 of a bit period.

The SIR receive decoder demodulates the return-to-zero bit stream from the infrared detector and outputs the received NRZ serial bit stream to USART. The decoder input is normally HIGH (marking state) in the Idle state. The transmit encoder output has the opposite polarity to the decoder input. A start bit is detected when the decoder input is low.

- IrDA is a half duplex communication protocol. If the Transmitter is busy (i.e. the USART is sending data to the IrDA encoder), any data on the IrDA receive line will be ignored by the IrDA decoder and if the Receiver is busy (USART is receiving decoded data from the USART), data on the TX from the USART to IrDA will not be encoded by IrDA. While receiving data, transmission should be avoided as the data to be transmitted could be corrupted.
- A '0 is transmitted as a high pulse and a '1 is transmitted as a '0. The width of the pulse is specified as 3/16th of the selected bit period in normal mode (see [Figure 185](#)).
- The SIR decoder converts the IrDA compliant receive signal into a bit stream for USART.
- The SIR receive logic interprets a high state as a logic one and low pulses as logic zeros.
- The transmit encoder output has the opposite polarity to the decoder input. The SIR output is in low state when Idle.
- The IrDA specification requires the acceptance of pulses greater than 1.41 us. The acceptable pulse width is programmable. Glitch detection logic on the receiver end filters out pulses of width less than 2 PSC periods (PSC is the prescaler value programmed in the IrDA low-power Baud Register, USART\_GTPR). Pulses of width less than 1 PSC period are always rejected, but those of width greater than one and less than two periods may be accepted or rejected, those greater than 2 periods will be accepted as a pulse. The IrDA encoder/decoder doesn't work when PSC=0.
- The receiver can communicate with a low-power transmitter.
- In IrDA mode, the STOP bits in the USART\_CR2 register must be configured to "1 stop bit".

**IrDA low-power mode**

**Transmitter:**

In low-power mode the pulse width is not maintained at 3/16 of the bit period. Instead, the width of the pulse is 3 times the low-power baud rate which can be a minimum of 1.42 MHz. Generally this value is 1.8432 MHz (1.42 MHz < PSC < 2.12 MHz). A low-power mode programmable divisor divides the system clock to achieve this value.

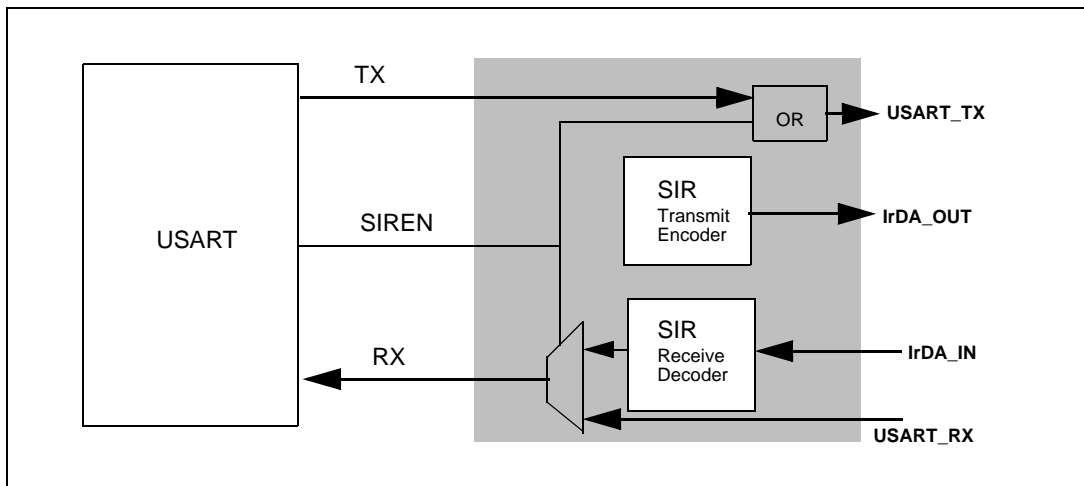
**Receiver:**

Receiving in low-power mode is similar to receiving in normal mode. For glitch detection the USART should discard pulses of duration shorter than 1/PSC. A valid low is accepted only if its duration is greater than 2 periods of the IrDA low-power Baud clock (PSC value in USART\_GTPR).

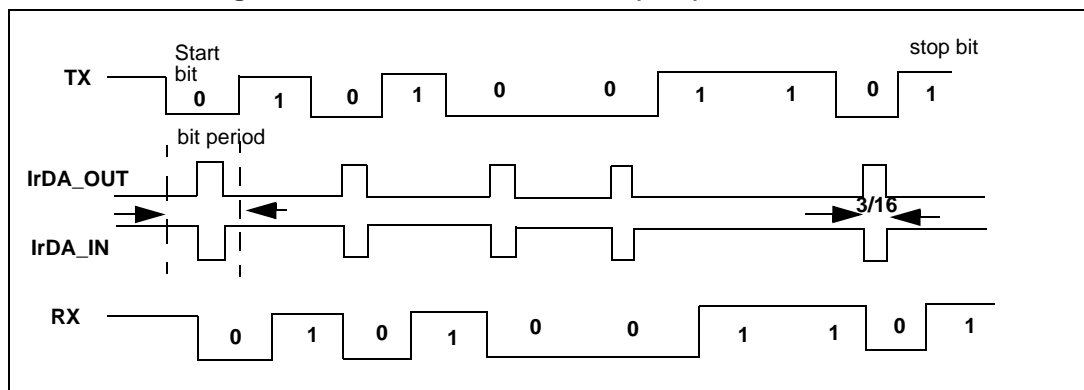
*Note: A pulse of width less than two and greater than one PSC period(s) may or may not be rejected.*

*The receiver set up time should be managed by software. The IrDA physical layer specification specifies a minimum of 10 ms delay between transmission and reception (IrDA is a half duplex protocol).*

**Figure 184. IrDA SIR ENDEC- block diagram**



**Figure 185. IrDA data modulation (3/16) -Normal mode**



### 19.3.13 Continuous communication using DMA

The USART is capable of continuous communication using the DMA. The DMA requests for Rx buffer and Tx buffer are generated independently.

#### Transmission using DMA

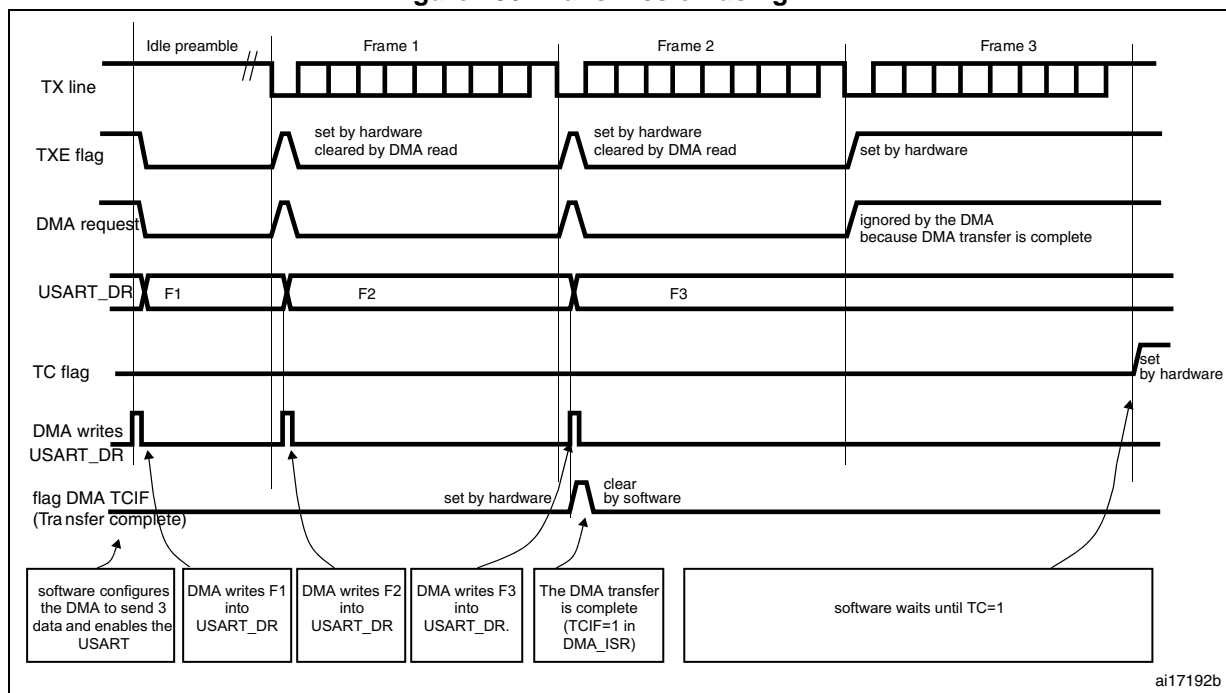
DMA mode can be enabled for transmission by setting DMAT bit in the USART\_CR3 register. Data is loaded from a SRAM area configured using the DMA peripheral (refer to the DMA specification) to the USART\_DR register whenever the TXE bit is set. To map a DMA channel for USART transmission, use the following procedure (x denotes the channel number):

1. Write the USART\_DR register address in the DMA control register to configure it as the destination of the transfer. The data will be moved to this address from memory after each TXE event.
2. Write the memory address in the DMA control register to configure it as the source of the transfer. The data will be loaded into the USART\_DR register from this memory area after each TXE event.
3. Configure the total number of bytes to be transferred to the DMA control register.
4. Configure the channel priority in the DMA register
5. Configure DMA interrupt generation after half/ full transfer as required by the application.
6. Clear the TC bit in the SR register by writing 0 to it.
7. Activate the channel in the DMA register.

When the number of data transfers programmed in the DMA Controller is reached, the DMA controller generates an interrupt on the DMA channel interrupt vector.

In transmission mode, once the DMA has written all the data to be transmitted (the TCIF flag is set in the DMA\_ISR register), the TC flag can be monitored to make sure that the USART communication is complete. This is required to avoid corrupting the last transmission before disabling the USART or entering the Stop mode. The software must wait until TC=1. The TC flag remains cleared during all data transfers and it is set by hardware at the last frame's end of transmission.

Figure 186. Transmission using DMA



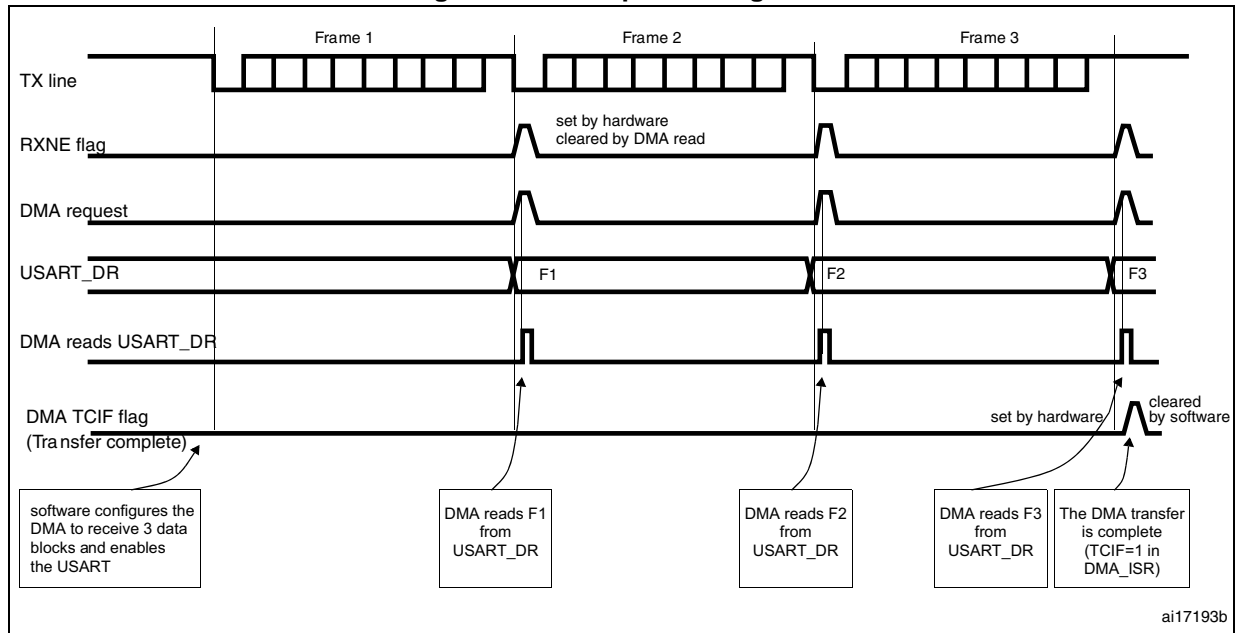
### Reception using DMA

DMA mode can be enabled for reception by setting the DMAR bit in USART\_CR3 register. Data is loaded from the USART\_DR register to a SRAM area configured using the DMA peripheral (refer to the DMA specification) whenever a data byte is received. To map a DMA channel for USART reception, use the following procedure:

1. Write the USART\_DR register address in the DMA control register to configure it as the source of the transfer. The data will be moved from this address to the memory after each RXNE event.
2. Write the memory address in the DMA control register to configure it as the destination of the transfer. The data will be loaded from USART\_DR to this memory area after each RXNE event.
3. Configure the total number of bytes to be transferred in the DMA control register.
4. Configure the channel priority in the DMA control register
5. Configure interrupt generation after half/ full transfer as required by the application.
6. Activate the channel in the DMA control register.

When the number of data transfers programmed in the DMA Controller is reached, the DMA controller generates an interrupt on the DMA channel interrupt vector. The DMAR bit should be cleared by software in the USART\_CR3 register during the interrupt subroutine.

Figure 187. Reception using DMA



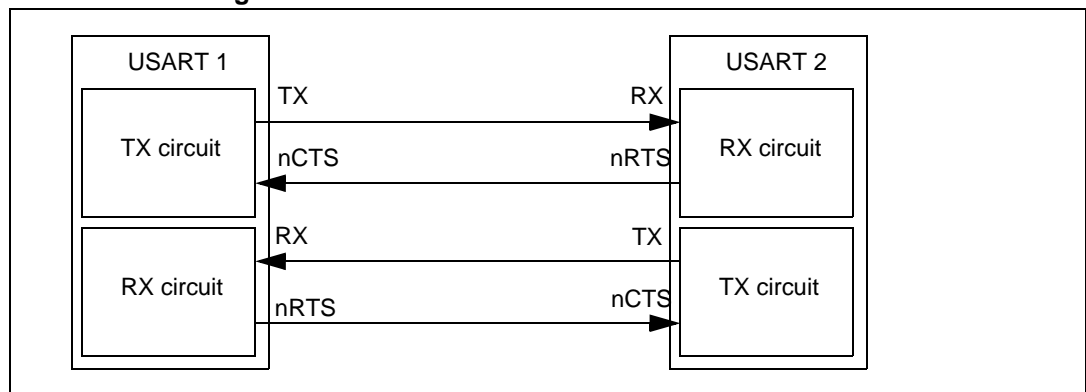
**Error flagging and interrupt generation in multibuffer communication**

In case of multibuffer communication if any error occurs during the transaction the error flag will be asserted after the current byte. An interrupt will be generated if the interrupt enable flag is set. For framing error, overrun error and noise flag which are asserted with RXNE in case of single byte reception, there will be separate error flag interrupt enable bit (EIE bit in the USART\_CR3 register), which if set will issue an interrupt after the current byte with either of these errors.

**19.3.14 Hardware flow control**

It is possible to control the serial data flow between 2 devices by using the nCTS input and the nRTS output. The [Figure 188](#) shows how to connect 2 devices in this mode:

Figure 188. Hardware flow control between 2 USARTs



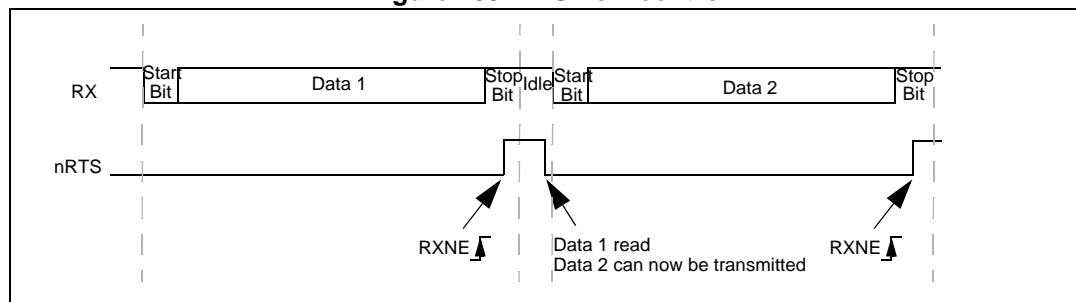
RTS and CTS flow control can be enabled independently by writing respectively RTSE and CTSE bits to 1 (in the USART\_CR3 register).



### RTS flow control

If the RTS flow control is enabled (RTSE=1), then nRTS is asserted (tied low) as long as the USART receiver is ready to receive a new data. When the receive register is full, nRTS is deasserted, indicating that the transmission is expected to stop at the end of the current frame. *Figure 189* shows an example of communication with RTS flow control enabled.

Figure 189. RTS flow control

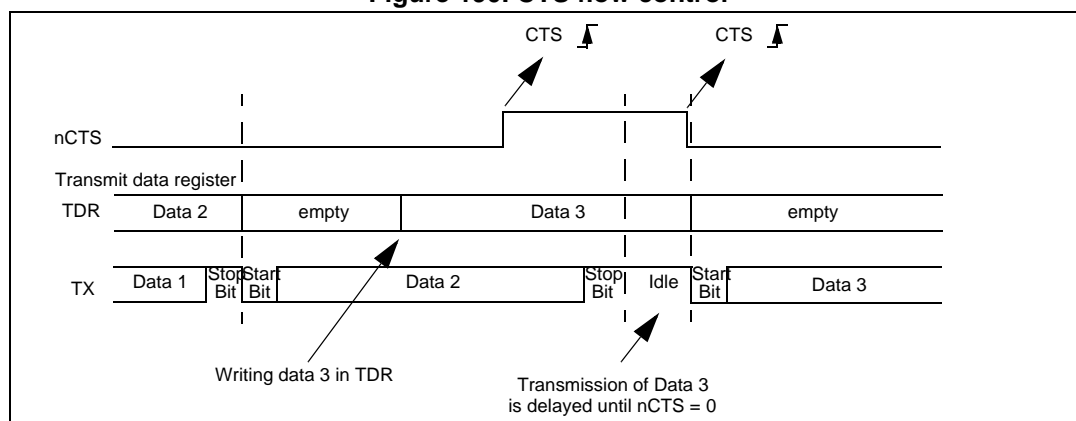


### CTS flow control

If the CTS flow control is enabled (CTSE=1), then the transmitter checks the nCTS input before transmitting the next frame. If nCTS is asserted (tied low), then the next data is transmitted (assuming that a data is to be transmitted, in other words, if TXE=0), else the transmission does not occur. When nCTS is deasserted during a transmission, the current transmission is completed before the transmitter stops.

When CTSE=1, the CTSIF status bit is automatically set by hardware as soon as the nCTS input toggles. It indicates when the receiver becomes ready or not ready for communication. An interrupt is generated if the CTSIE bit in the USART\_CR3 register is set. The figure below shows an example of communication with CTS flow control enabled.

Figure 190. CTS flow control



*Note:* **Special behavior of break frames:** when the CTS flow is enabled, the transmitter does not check the nCTS input state to send a break.

## 19.4 USART interrupts

Table 87. USART interrupt requests

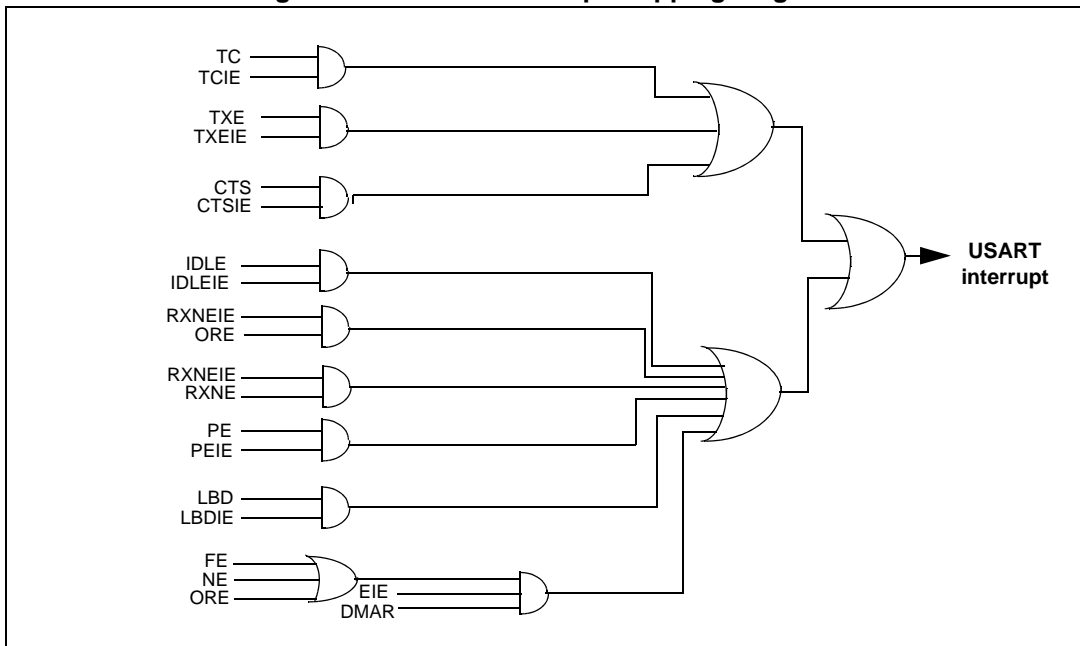
Interrupt event	Event flag	Enable control bit
Transmit Data Register Empty	TXE	TXEIE
CTS flag	CTS	CTSIE
Transmission Complete	TC	TCIE
Received Data Ready to be Read	RXNE	RXNEIE
Overrun Error Detected	ORE	
Idle Line Detected	IDLE	IDLEIE
Parity Error	PE	PEIE
Break Flag	LBD	LBDIE
Noise Flag, Overrun error and Framing Error in multibuffer communication	NF or ORE or FE	EIE

The USART interrupt events are connected to the same interrupt vector (see [Figure 191](#)).

- During transmission: Transmission Complete, Clear to Send or Transmit Data Register empty interrupt.
- While receiving: Idle Line detection, Overrun error, Receive Data register not empty, Parity error, LIN break detection, Noise Flag (only in multi buffer communication) and Framing Error (only in multi buffer communication).

These events generate an interrupt if the corresponding Enable Control Bit is set.

Figure 191. USART interrupt mapping diagram



## 19.5 USART mode configuration

Table 88. USART mode configuration<sup>(1)</sup>

USART modes	USART1	USART2	USART6
Asynchronous mode	X	X	X
Hardware flow control	X	X	X
Multibuffer communication (DMA)	X	X	X
Multiprocessor communication	X	X	X
Synchronous	X	X	X
Smartcard	X	X	X
Half-duplex (single-wire mode)	X	X	X
IrDA	X	X	X
LIN	X	X	X

1. X = supported; NA = not applicable.

## 19.6 USART registers

Refer to [Section 1.1 on page 34](#) for a list of abbreviations used in register descriptions.

The peripheral registers have to be accessed by half-words (16 bits) or words (32 bits).

### 19.6.1 Status register (USART\_SR)

Address offset: 0x00

Reset value: 0x00C0 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved															
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved						CTS	LBD	TXE	TC	RXNE	IDLE	ORE	NF	FE	PE
Reserved						rc_w0	rc_w0	r	rc_w0	rc_w0	r	r	r	r	r

Bits 31:10 Reserved, must be kept at reset value

Bit 9 **CTS**: CTS flag

This bit is set by hardware when the nCTS input toggles, if the CTSE bit is set. It is cleared by software (by writing it to 0). An interrupt is generated if CTSIE=1 in the USART\_CR3 register.

*Note:* 0: No change occurred on the nCTS status line  
 1: A change occurred on the nCTS status line

Bit 8 **LBD**: LIN break detection flag

This bit is set by hardware when the LIN break is detected. It is cleared by software (by writing it to 0). An interrupt is generated if LBDIE = 1 in the USART\_CR2 register.

0: LIN Break not detected  
 1: LIN break detected

*Note:* An interrupt is generated when LBD=1 if LBDIE=1

**Bit 7 TXE:** Transmit data register empty

This bit is set by hardware when the content of the TDR register has been transferred into the shift register. An interrupt is generated if the TXEIE bit =1 in the USART\_CR1 register. It is cleared by a write to the USART\_DR register.

0: Data is not transferred to the shift register

1: Data is transferred to the shift register)

*Note: This bit is used during single buffer transmission.*

**Bit 6 TC:** Transmission complete

This bit is set by hardware if the transmission of a frame containing data is complete and if TXE is set. An interrupt is generated if TCIE=1 in the USART\_CR1 register. It is cleared by a software sequence (a read from the USART\_SR register followed by a write to the USART\_DR register). The TC bit can also be cleared by writing a '0' to it. This clearing sequence is recommended only for multibuffer communication.

0: Transmission is not complete

1: Transmission is complete

**Bit 5 RXNE:** Read data register not empty

This bit is set by hardware when the content of the RDR shift register has been transferred to the USART\_DR register. An interrupt is generated if RXNEIE=1 in the USART\_CR1 register. It is cleared by a read to the USART\_DR register. The RXNE flag can also be cleared by writing a zero to it. This clearing sequence is recommended only for multibuffer communication.

0: Data is not received

1: Received data is ready to be read.

**Bit 4 IDLE:** IDLE line detected

This bit is set by hardware when an Idle Line is detected. An interrupt is generated if the IDLEIE=1 in the USART\_CR1 register. It is cleared by a software sequence (an read to the USART\_SR register followed by a read to the USART\_DR register).

0: No Idle Line is detected

1: Idle Line is detected

*Note: The IDLE bit will not be set again until the RXNE bit has been set itself (i.e. a new idle line occurs).*

**Bit 3 ORE:** Overrun error

This bit is set by hardware when the word currently being received in the shift register is ready to be transferred into the RDR register while RXNE=1. An interrupt is generated if RXNEIE=1 in the USART\_CR1 register. It is cleared by a software sequence (an read to the USART\_SR register followed by a read to the USART\_DR register).

0: No Overrun error

1: Overrun error is detected

*Note: When this bit is set, the RDR register content will not be lost but the shift register will be overwritten. An interrupt is generated on ORE flag in case of Multi Buffer communication if the EIE bit is set.*

**Bit 2 NF:** Noise detected flag

This bit is set by hardware when noise is detected on a received frame. It is cleared by a software sequence (an read to the USART\_SR register followed by a read to the USART\_DR register).

0: No noise is detected

1: Noise is detected

*Note: This bit does not generate interrupt as it appears at the same time as the RXNE bit which itself generates an interrupting interrupt is generated on NF flag in case of Multi Buffer communication if the EIE bit is set.*

*Note: When the line is noise-free, the NF flag can be disabled by programming the ONEBIT bit to 1 to increase the USART tolerance to deviations (Refer to [Section 19.3.5: USART receiver tolerance to clock deviation on page 524](#)).*

**Bit 1 FE:** Framing error

This bit is set by hardware when a de-synchronization, excessive noise or a break character is detected. It is cleared by a software sequence (an read to the USART\_SR register followed by a read to the USART\_DR register).

0: No Framing error is detected

1: Framing error or break character is detected

*Note: This bit does not generate interrupt as it appears at the same time as the RXNE bit which itself generates an interrupt. If the word currently being transferred causes both frame error and overrun error, it will be transferred and only the ORE bit will be set.*

*An interrupt is generated on FE flag in case of Multi Buffer communication if the EIE bit is set.*

**Bit 0 PE:** Parity error

This bit is set by hardware when a parity error occurs in receiver mode. It is cleared by a software sequence (a read from the status register followed by a read or write access to the USART\_DR data register). The software must wait for the RXNE flag to be set before clearing the PE bit.

An interrupt is generated if PEIE = 1 in the USART\_CR1 register.

0: No parity error

1: Parity error

### 19.6.2 Data register (USART\_DR)

Address offset: 0x04

Reset value: 0xFFFF XXXX

Bits 31:9 Reserved, must be kept at reset value

Bits 8:0 **DR[8:0]**: Data value

Contains the Received or Transmitted data character, depending on whether it is read from or written to.

The Data register performs a double function (read and write) since it is composed of two registers, one for transmission (TDR) and one for reception (RDR)

The TDR register provides the parallel interface between the internal bus and the output shift register (see Figure 1).

The RDR register provides the parallel interface between the input shift register and the internal bus.

When transmitting with the parity enabled (PCE bit set to 1 in the USART\_CR1 register), the value written in the MSB (bit 7 or bit 8 depending on the data length) has no effect because it is replaced by the parity.

When receiving with the parity enabled, the value read in the MSB bit is the received parity bit.

### 19.6.3 Baud rate register (USART\_BRR)

*Note: The baud counters stop counting if the TE or RE bits are disabled respectively.*

Address offset: 0x08

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved															
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
DIV_Mantissa[11:0]												DIV_Fraction[3:0]			
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 31:16 Reserved, must be kept at reset value

Bits 15:4 **DIV\_Mantissa[11:0]**: mantissa of USARTDIV

These 12 bits define the mantissa of the USART Divider (USARTDIV)

Bits 3:0 **DIV\_Fraction[3:0]**: fraction of USARTDIV

These 4 bits define the fraction of the USART Divider (USARTDIV). When OVER8=1, the DIV\_Fraction3 bit is not considered and must be kept cleared.

### 19.6.4 Control register 1 (USART\_CR1)

Address offset: 0x0C

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved															
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
OVER8	Reserved	UE	M	WAKE	PCE	PS	PEIE	TXEIE	TCIE	RXNEIE	IDLEIE	TE	RE	RWU	SBK
rw	Res.	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw



Bits 31:16 Reserved, must be kept at reset value

Bit 15 **OVER8**: Oversampling mode

0: oversampling by 16

1: oversampling by 8

*Note: Oversampling by 8 is not available in the Smartcard, IrDA and LIN modes: when SCEN=1, IREN=1 or LINEN=1 then OVER8 is forced to '0 by hardware.*

Bit 14 Reserved, must be kept at reset value

Bit 13 **UE**: USART enable

When this bit is cleared, the USART prescalers and outputs are stopped and the end of the current byte transfer in order to reduce power consumption. This bit is set and cleared by software.

0: USART prescaler and outputs disabled

1: USART enabled

Bit 12 **M**: Word length

This bit determines the word length. It is set or cleared by software.

0: 1 Start bit, 8 Data bits, n Stop bit

1: 1 Start bit, 9 Data bits, n Stop bit

*Note: The M bit must not be modified during a data transfer (both transmission and reception)*

Bit 11 **WAKE**: Wakeup method

This bit determines the USART wakeup method, it is set or cleared by software.

0: Idle Line

1: Address Mark

Bit 10 **PCE**: Parity control enable

This bit selects the hardware parity control (generation and detection). When the parity control is enabled, the computed parity is inserted at the MSB position (9th bit if M=1; 8th bit if M=0) and parity is checked on the received data. This bit is set and cleared by software. Once it is set, PCE is active after the current byte (in reception and in transmission).

0: Parity control disabled

1: Parity control enabled

Bit 9 **PS**: Parity selection

This bit selects the odd or even parity when the parity generation/detection is enabled (PCE bit set). It is set and cleared by software. The parity will be selected after the current byte.

0: Even parity

1: Odd parity

Bit 8 **PEIE**: PE interrupt enable

This bit is set and cleared by software.

0: Interrupt is inhibited

1: An USART interrupt is generated whenever PE=1 in the USART\_SR register

Bit 7 **TXEIE**: TXE interrupt enable

This bit is set and cleared by software.

0: Interrupt is inhibited

1: An USART interrupt is generated whenever TXE=1 in the USART\_SR register

Bit 6 **TCIE**: Transmission complete interrupt enable

This bit is set and cleared by software.

0: Interrupt is inhibited

1: An USART interrupt is generated whenever TC=1 in the USART\_SR register

**Bit 5 RXNEIE:** RXNE interrupt enable

This bit is set and cleared by software.

0: Interrupt is inhibited

1: An USART interrupt is generated whenever ORE=1 or RXNE=1 in the USART\_SR register

**Bit 4 IDLEIE:** IDLE interrupt enable

This bit is set and cleared by software.

0: Interrupt is inhibited

1: An USART interrupt is generated whenever IDLE=1 in the USART\_SR register

**Bit 3 TE:** Transmitter enable

This bit enables the transmitter. It is set and cleared by software.

0: Transmitter is disabled

1: Transmitter is enabled

*Note: During transmission, a “0” pulse on the TE bit (“0” followed by “1”) sends a preamble (idle line) after the current word, except in smartcard mode.*

*When TE is set, there is a 1 bit-time delay before the transmission starts.*

**Bit 2 RE:** Receiver enable

This bit enables the receiver. It is set and cleared by software.

0: Receiver is disabled

1: Receiver is enabled and begins searching for a start bit

**Bit 1 RWU:** Receiver wakeup

This bit determines if the USART is in mute mode or not. It is set and cleared by software and can be cleared by hardware when a wakeup sequence is recognized.

0: Receiver in active mode

1: Receiver in mute mode

*Note: Before selecting Mute mode (by setting the RWU bit) the USART must first receive a data byte, otherwise it cannot function in Mute mode with wakeup by Idle line detection.*

*In Address Mark Detection wakeup configuration (WAKE bit=1) the RWU bit cannot be modified by software while the RXNE bit is set.*

**Bit 0 SBK:** Send break

This bit set is used to send break characters. It can be set and cleared by software. It should be set by software, and will be reset by hardware during the stop bit of break.

0: No break character is transmitted

1: Break character will be transmitted



### 19.6.5 Control register 2 (USART\_CR2)

Address offset: 0x10

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved															
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Res.	LINEN	STOP[1:0]		CLKEN	CPOL	CPHA	LBCL	Res.	LBDIE	LBDL	Res.	ADD[3:0]			
	rw	rw	rw	rw	rw	rw	rw		rw	rw	rw	rw	rw	rw	rw

Bits 31:15 Reserved, must be kept at reset value

Bit 14 **LINEN**: LIN mode enable

This bit is set and cleared by software.

0: LIN mode disabled

1: LIN mode enabled

The LIN mode enables the capability to send LIN Synch Breaks (13 low bits) using the SBK bit in the USART\_CR1 register, and to detect LIN Sync breaks.

Bits 13:12 **STOP**: STOP bits

These bits are used for programming the stop bits.

00: 1 Stop bit

01: 0.5 Stop bit

10: 2 Stop bits

*Note:* 11: 1.5 Stop bit

Bit 11 **CLKEN**: Clock enable

This bit allows the user to enable the SCLK pin.

0: SCLK pin disabled

1: SCLK pin enabled

Bit 10 **CPOL**: Clock polarity

This bit allows the user to select the polarity of the clock output on the SCLK pin in synchronous mode. It works in conjunction with the CPHA bit to produce the desired clock/data relationship

0: Steady low value on SCLK pin outside transmission window.

1: Steady high value on SCLK pin outside transmission window.

Bit 9 **CPHA**: Clock phase

This bit allows the user to select the phase of the clock output on the SCLK pin in synchronous mode. It works in conjunction with the CPOL bit to produce the desired clock/data relationship (see figures 179 to 180)

*Note:* 0: The first clock transition is the first data capture edge

1: The second clock transition is the first data capture edge

Bit 8 **LBCL**: Last bit clock pulse

This bit allows the user to select whether the clock pulse associated with the last data bit transmitted (MSB) has to be output on the SCLK pin in synchronous mode.

0: The clock pulse of the last data bit is not output to the SCLK pin

1: The clock pulse of the last data bit is output to the SCLK pin

*1: The last bit is the 8th or 9th data bit transmitted depending on the 8 or 9 bit format selected by the M bit in the USART\_CR1 register.*

Bit 7 Reserved, must be kept at reset value

Bit 6 **LBDIE**: LIN break detection interrupt enable  
 Break interrupt mask (break detection using break delimiter).  
 0: Interrupt is inhibited  
 1: An interrupt is generated whenever LBD=1 in the USART\_SR register

Bit 5 **LBDL**: *lin* break detection length  
 This bit is for selection between 11 bit or 10 bit break detection.  
 0: 10-bit break detection  
 1: 11-bit break detection

Bit 4 Reserved, must be kept at reset value

Bits 3:0 **ADD[3:0]**: Address of the USART node  
 This bit-field gives the address of the USART node.  
 This is used in multiprocessor communication during mute mode, for wake up with address mark detection.

*Note: These 3 bits (CPOL, CPHA, LBCL) should not be written while the transmitter is enabled.*

### 19.6.6 Control register 3 (USART\_CR3)

Address offset: 0x14

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved															
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved				ONEBIT	CTSIE	CTSE	RTSE	DMAT	DMAR	SCEN	NACK	HDSEL	IRLP	IREN	EIE
				rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 31:12 Reserved, must be kept at reset value

Bit 11 **ONEBIT**: One sample bit method enable  
 This bit allows the user to select the sample method. When the one sample bit method is selected the noise detection flag (NF) is disabled.  
 0: Three sample bit method  
 1: One sample bit method

Bit 10 **CTSIE**: CTS interrupt enable  
*Note:* 0: Interrupt is inhibited  
 1: An interrupt is generated whenever CTS=1 in the USART\_SR register

Bit 9 **CTSE**: CTS enable  
 0: CTS hardware flow control disabled  
*Note:* 1: CTS mode enabled, data is only transmitted when the nCTS input is asserted (tied to 0). If the nCTS input is deasserted while a data is being transmitted, then the transmission is completed before stopping. If a data is written into the data register while nCTS is deasserted, the transmission is postponed until nCTS is asserted.

Bit 8 **RTSE**: RTS enable  
 0: RTS hardware flow control disabled  
*Note:* 1: RTS interrupt enabled, data is only requested when there is space in the receive buffer. The transmission of data is expected to cease after the current character has been transmitted. The nRTS output is asserted (tied to 0) when a data can be received.



- Bit 7 **DMAT**: DMA enable transmitter  
This bit is set/reset by software  
1: DMA mode is enabled for transmission.  
0: DMA mode is disabled for transmission.
- Bit 6 **DMAR**: DMA enable receiver  
This bit is set/reset by software  
1: DMA mode is enabled for reception  
0: DMA mode is disabled for reception
- Bit 5 **SCEN**: Smartcard mode enable  
This bit is used for enabling Smartcard mode.  
*Note:* 0: Smartcard Mode disabled  
1: Smartcard Mode enabled
- Bit 4 **NACK**: Smartcard NACK enable  
*Note:* 0: NACK transmission in case of parity error is disabled  
1: NACK transmission during parity error is enabled
- Bit 3 **HDSEL**: Half-duplex selection  
Selection of Single-wire Half-duplex mode  
0: Half duplex mode is not selected  
1: Half duplex mode is selected
- Bit 2 **IRLP**: IrDA low-power  
This bit is used for selecting between normal and low-power IrDA modes  
0: Normal mode  
1: Low-power mode
- Bit 1 **IREN**: IrDA mode enable  
This bit is set and cleared by software.  
0: IrDA disabled  
1: IrDA enabled
- Bit 0 **EIE**: Error interrupt enable  
Error Interrupt Enable Bit is required to enable interrupt generation in case of a framing error, overrun error or noise flag (FE=1 or ORE=1 or NF=1 in the USART\_SR register) in case of Multi Buffer Communication (DMAR=1 in the USART\_CR3 register).  
0: Interrupt is inhibited  
1: An interrupt is generated whenever DMAR=1 in the USART\_CR3 register and FE=1 or ORE=1 or NF=1 in the USART\_SR register.

### 19.6.7 Guard time and prescaler register (USART\_GTPR)

Address offset: 0x18

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved															
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
GT[7:0]								PSC[7:0]							
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 31:16 Reserved, must be kept at reset value

Bits 15:8 **GT[7:0]**: Guard time value

This bit-field gives the Guard time value in terms of number of baud clocks.

*Note:* This is used in Smartcard mode. The Transmission Complete flag is set after this guard time value.

Bits 7:0 **PSC[7:0]**: Prescaler value

– **In IrDA Low-power mode:**

**PSC[7:0]** = IrDA Low-Power Baud Rate

Used for programming the prescaler for dividing the system clock to achieve the low-power frequency:

The source clock is divided by the value given in the register (8 significant bits):

00000000: Reserved - do not program this value

00000001: divides the source clock by 1

00000010: divides the source clock by 2

...

– **In normal IrDA mode:** PSC must be set to 00000001.

– In smartcard mode:

**PSC[4:0]**: Prescaler value

Used for programming the prescaler for dividing the system clock to provide the smartcard clock.

The value given in the register (5 significant bits) is multiplied by 2 to give the division factor of the source clock frequency:

00000: Reserved - do not program this value

00001: divides the source clock by 2

00010: divides the source clock by 4

00011: divides the source clock by 6

...

*Note:* 1: Bits [7:5] have no effect if Smartcard mode is used.

### 19.6.8 USART register map

The table below gives the USART register map and reset values.

**Table 89. USART register map and reset values**

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0																			
0x00	USART_SR	Reserved																						CTS	LBD	TXE	TC	RXNE	IDLE	ORE	NF	FE	PE																			
	Reset value																							0	0	1	1	0	0	0	0	0	0																			
0x04	USART_DR	Reserved																						DR[8:0]																												
	Reset value																							0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x08	USART_BRR	Reserved														DIV_Mantissa[15:4]						DIV_Fraction [3:0]																														
	Reset value															0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0						
0x0C	USART_CR1	Reserved														OVER8	Reserved	UE	M	WAKE	PCE	PS	PEIE	TXEIE	TCIE	RXNEIE	IDLEIE	TE	RE	RWU	SBK																					
	Reset value															0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0					
0x10	USART_CR2	Reserved														LINEN	STOP [1:0]	CLKEN	CPOL	CPHA	LBCL	Reserved	LBDIE	LBDL	Reserved	ADD[3:0]																										
	Reset value															0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0					
0x14	USART_CR3	Reserved														ONEBIT	CTSIE	CTSE	RTSE	DMAT	DMAR	SCEN	NACK	HDSSEL	IRLP	IREN	EIE																									
	Reset value															0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0					
0x18	USART_GTPR	Reserved														GT[7:0]						PSC[7:0]																														
	Reset value															0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0					

Refer to [Table 1 on page 38](#) for the register boundary addresses.



## 20 Serial peripheral interface (SPI)

### 20.1 SPI introduction

The SPI interface provides two main functions, supporting either the SPI protocol or the I<sup>2</sup>S audio protocol. By default, it is the SPI function that is selected. It is possible to switch the interface from SPI to I<sup>2</sup>S by software.

The serial peripheral interface (SPI) allows half/ full-duplex, synchronous, serial communication with external devices. The interface can be configured as the master and in this case it provides the communication clock (SCK) to the external slave device. The interface is also capable of operating in multimaster configuration.

It may be used for a variety of purposes, including simplex synchronous transfers on two lines with a possible bidirectional data line or reliable communication using CRC checking.

The I<sup>2</sup>S is also a synchronous serial communication interface. It can address four different audio standards including the I<sup>2</sup>S Philips standard, the MSB- and LSB-justified standards, and the PCM standard. It can operate as a slave or a master device in full-duplex mode (using 4 pins) or in half-duplex mode (using 3 pins). Master clock can be provided by the interface to an external slave component when the I<sup>2</sup>S is configured as the communication master.

---

**Warning:** Since some SPI1 and SPI3/I2S3 pins may be mapped onto some pins used by the JTAG interface (SPI1\_NSS onto JTDI, SPI3\_NSS/I2S3\_WS onto JTDI and SPI3\_SCK/I2S3\_CK onto JTDO), you may either:

- map SPI/I2S onto other pins
- disable the JTAG and use the SWD interface prior to configuring the pins listed as SPI I/Os (when debugging the application) or
- disable both JTAG/SWD interfaces (for standalone applications).

For more information on the configuration of the JTAG/SWD interface pins, please refer to [Section 8.3.2: I/O pin multiplexer and mapping](#).

---

## 20.2 SPI and I<sup>2</sup>S main features

### 20.2.1 SPI features

- Full-duplex synchronous transfers on three lines
- Simplex synchronous transfers on two lines with or without a bidirectional data line
- 8- or 16-bit transfer frame format selection
- Master or slave operation
- Multimaster mode capability
- 8 master mode baud rate prescalers ( $f_{PCLK}/2$  max.)
- Slave mode frequency ( $f_{PCLK}/2$  max)
- Faster communication for both master and slave
- NSS management by hardware or software for both master and slave: dynamic change of master/slave operations
- Programmable clock polarity and phase
- Programmable data order with MSB-first or LSB-first shifting
- Dedicated transmission and reception flags with interrupt capability
- SPI bus busy status flag
- SPI TI mode
- Hardware CRC feature for reliable communication:
  - CRC value can be transmitted as last byte in Tx mode
  - Automatic CRC error checking for last received byte
- Master mode fault, overrun and CRC error flags with interrupt capability
- 1-byte transmission and reception buffer with DMA capability: Tx and Rx requests

## 20.2.2 I<sup>2</sup>S features

- Full duplex communication
- Half-duplex communication (only transmitter or receiver)
- Master or slave operations
- 8-bit programmable linear prescaler to reach accurate audio sample frequencies (from 8 kHz to 192 kHz)
- Data format may be 16-bit, 24-bit or 32-bit
- Packet frame is fixed to 16-bit (16-bit data frame) or 32-bit (16-bit, 24-bit, 32-bit data frame) by audio channel
- Programmable clock polarity (steady state)
- Underrun flag in slave transmission mode, overrun flag in reception mode (master and slave), and Frame Error flag in reception and transmission mode (slave only)
- 16-bit register for transmission and reception with one data register for both channel sides
- Supported I<sup>2</sup>S protocols:
  - I<sup>2</sup>S Philips standard
  - MSB-justified standard (left-justified)
  - LSB-justified standard (right-justified)
  - PCM standard (with short and long frame synchronization on 16-bit channel frame or 16-bit data frame extended to 32-bit channel frame)
- Data direction is always MSB first
- DMA capability for transmission and reception (16-bit wide)
- Master clock may be output to drive an external audio component. Ratio is fixed at  $256 \times F_S$  (where  $F_S$  is the audio sampling frequency)
- Both I<sup>2</sup>S (I2S2 and I2S3) have a dedicated PLL (PLLI2S) to generate an even more accurate clock.
- I<sup>2</sup>S (I2S2 and I2S3) clock can be derived from an external clock mapped on the I2S\_CKIN pin.

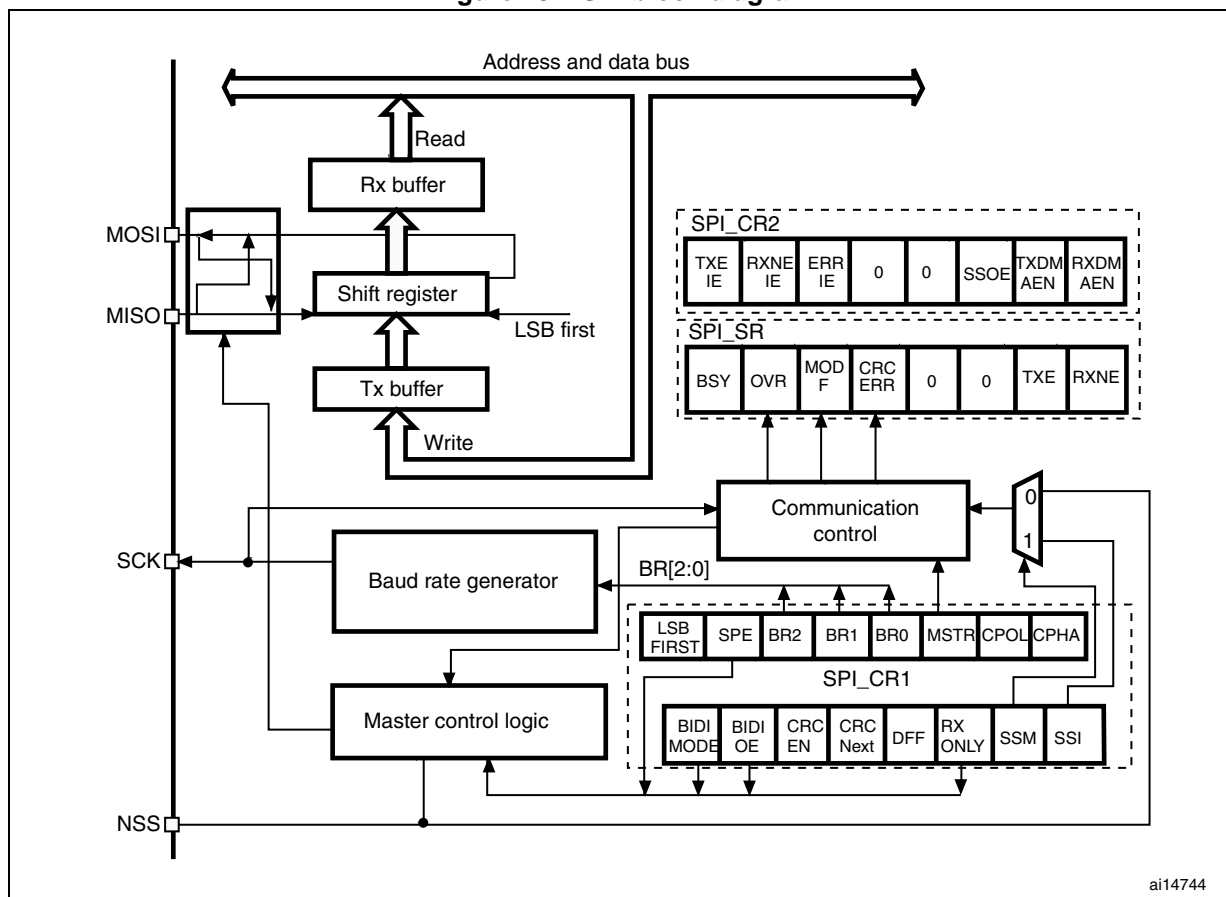


## 20.3 SPI functional description

### 20.3.1 General description

The block diagram of the SPI is shown in *Figure 192*.

Figure 192. SPI block diagram



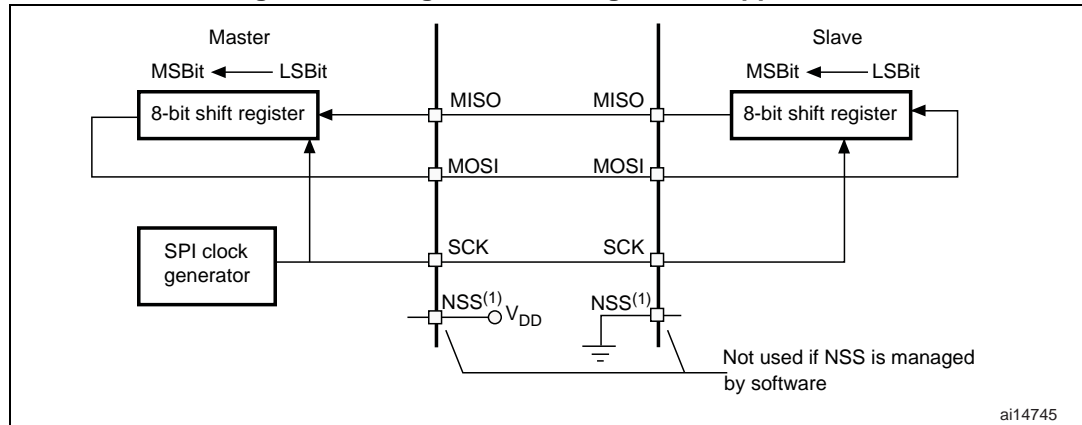
Usually, the SPI is connected to external devices through 4 pins:

- MISO: Master In / Slave Out data. This pin can be used to transmit data in slave mode and receive data in master mode.
- MOSI: Master Out / Slave In data. This pin can be used to transmit data in master mode and receive data in slave mode.
- SCK: Serial Clock output for SPI masters and input for SPI slaves.
- NSS: Slave select. This is an optional pin to select a slave device. This pin acts as a 'chip select' to let the SPI master communicate with slaves individually and to avoid contention on the data lines. Slave NSS inputs can be driven by standard IO ports on the master device. The NSS pin may also be used as an output if enabled (SSOE bit) and driven low if the SPI is in master configuration. In this manner, all NSS pins from devices connected to the Master NSS pin see a low level and become slaves when they are configured in NSS hardware mode. When configured in master mode with NSS configured as an input (MSTR=1 and SSOE=0) and if NSS is pulled low, the SPI enters the master mode fault state: the MSTR bit is automatically cleared and the

device is configured in slave mode (refer to [Section 20.3.10: Error flags on page 577](#)).

A basic example of interconnections between a single master and a single slave is illustrated in [Figure 193](#).

**Figure 193. Single master/ single slave application**



1. Here, the NSS pin is configured as an input.

The MOSI pins are connected together and the MISO pins are connected together. In this way data is transferred serially between master and slave (most significant bit first).

The communication is always initiated by the master. When the master device transmits data to a slave device via the MOSI pin, the slave device responds via the MISO pin. This implies full-duplex communication with both data out and data in synchronized with the same clock signal (which is provided by the master device via the SCK pin).

### Slave select (NSS) pin management

Hardware or software slave select management can be set using the SSM bit in the SPI\_CR1 register.

- Software NSS management (SSM = 1)
  - The slave select information is driven internally by the value of the SSI bit in the SPI\_CR1 register. The external NSS pin remains free for other application uses.
- Hardware NSS management (SSM = 0)
  - Two configurations are possible depending on the NSS output configuration (SSOE bit in register SPI\_CR2).
    - NSS output enabled (SSM = 0, SSOE = 1)
      - This configuration is used only when the device operates in master mode. The NSS signal is driven low when the master starts the communication and is kept low until the SPI is disabled.
    - NSS output disabled (SSM = 0, SSOE = 0)
      - This configuration allows multimaster capability for devices operating in master mode. For devices set as slave, the NSS pin acts as a classical NSS input: the slave is selected when NSS is low and deselected when NSS is high.

### Clock phase and clock polarity

Four possible timing relationships may be chosen by software, using the CPOL and CPHA bits in the SPI\_CR1 register. The CPOL (clock polarity) bit controls the steady state value of

the clock when no data is being transferred. This bit affects both master and slave modes. If CPOL is reset, the SCK pin has a low-level idle state. If CPOL is set, the SCK pin has a high-level idle state.

If the CPHA (clock phase) bit is set, the second edge on the SCK pin (falling edge if the CPOL bit is reset, rising edge if the CPOL bit is set) is the MSBit capture strobe. Data are latched on the occurrence of the second clock transition. If the CPHA bit is reset, the first edge on the SCK pin (falling edge if CPOL bit is set, rising edge if CPOL bit is reset) is the MSBit capture strobe. Data are latched on the occurrence of the first clock transition.

The combination of the CPOL (clock polarity) and CPHA (clock phase) bits selects the data capture clock edge.

*Figure 194*, shows an SPI transfer with the four combinations of the CPHA and CPOL bits. The diagram may be interpreted as a master or slave timing diagram where the SCK pin, the MISO pin, the MOSI pin are directly connected between the master and the slave device.

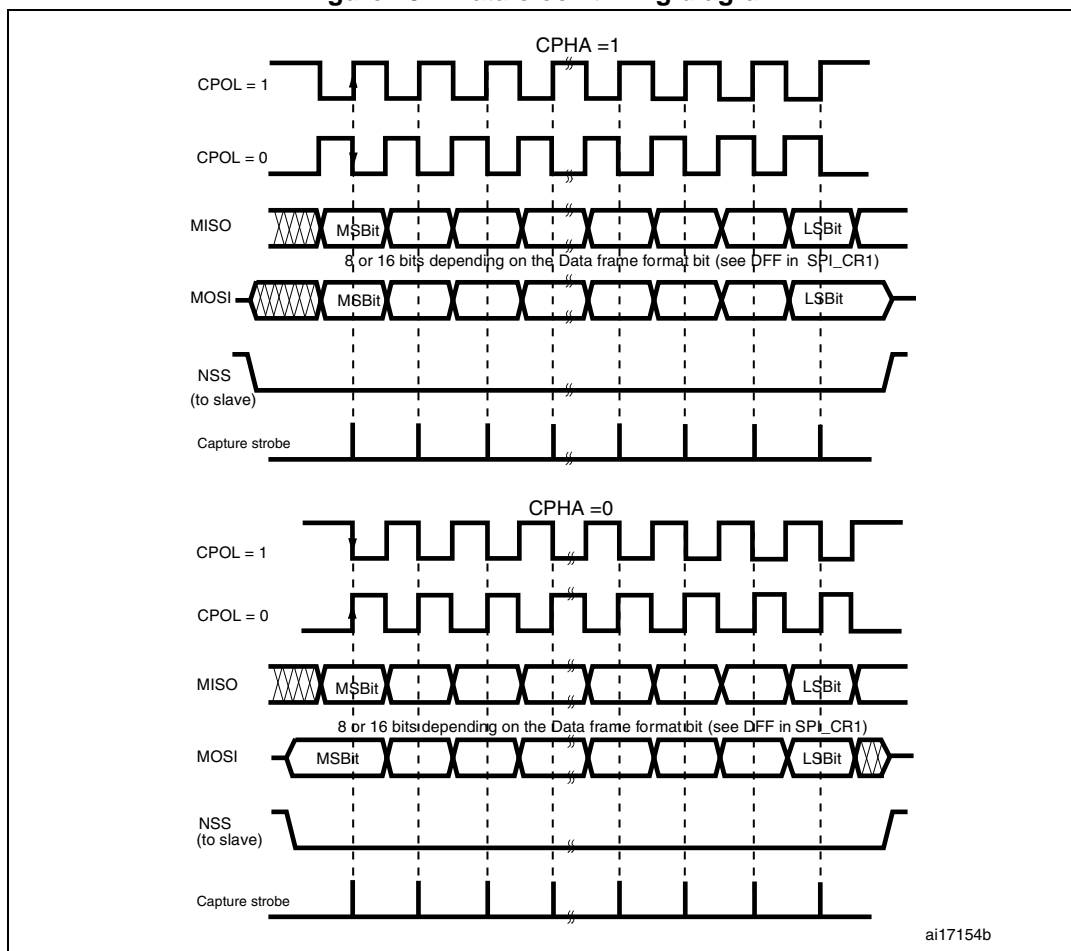
*Note:* *Prior to changing the CPOL/CPHA bits the SPI must be disabled by resetting the SPE bit.*

*Master and slave must be programmed with the same timing mode.*

*The idle state of SCK must correspond to the polarity selected in the SPI\_CR1 register (by pulling up SCK if CPOL=1 or pulling down SCK if CPOL=0).*

*The Data Frame Format (8- or 16-bit) is selected through the DFF bit in SPI\_CR1 register, and determines the data length during transmission/reception.*

Figure 194. Data clock timing diagram



1. These timings are shown with the LSBFIRST bit reset in the SPI\_CR1 register.

### Data frame format

Data can be shifted out either MSB-first or LSB-first depending on the value of the LSBFIRST bit in the SPI\_CR1 Register.

Each data frame is 8 or 16 bits long depending on the size of the data programmed using the DFF bit in the SPI\_CR1 register. The selected data frame format is applicable for transmission and/or reception.

### 20.3.2 Configuring the SPI in slave mode

In the slave configuration, the serial clock is received on the SCK pin from the master device. The value set in the BR[2:0] bits in the SPI\_CR1 register, does not affect the data transfer rate.

*Note: It is recommended to enable the SPI slave before the master sends the clock. If not, undesired data transmission might occur. The data register of the slave needs to be ready before the first edge of the communication clock or before the end of the ongoing communication. It is mandatory to have the polarity of the communication clock set to the steady state value before the slave and the master are enabled.*

Follow the procedure below to configure the SPI in slave mode:

### Procedure

1. Set the DFF bit to define 8- or 16-bit data frame format
2. Select the CPOL and CPHA bits to define one of the four relationships between the data transfer and the serial clock (see [Figure 194](#)). For correct data transfer, the CPOL and CPHA bits must be configured in the same way in the slave device and the master device. This step is not required when the TI mode is selected through the FRF bit in the SPI\_CR2 register.
3. The frame format (MSB-first or LSB-first depending on the value of the LSBFIRST bit in the SPI\_CR1 register) must be the same as the master device. This step is not required when TI mode is selected.
4. In Hardware mode (refer to [Slave select \(NSS\) pin management on page 557](#)), the NSS pin must be connected to a low level signal during the complete byte transmit sequence. In NSS software mode, set the SSM bit and clear the SSI bit in the SPI\_CR1 register. This step is not required when TI mode is selected.
5. Set the FRF bit in the SPI\_CR2 register to select the TI mode protocol for serial communications.
6. Clear the MSTR bit and set the SPE bit (both in the SPI\_CR1 register) to assign the pins to alternate functions.

In this configuration the MOSI pin is a data input and the MISO pin is a data output.

### Transmit sequence

The data byte is parallel-loaded into the Tx buffer during a write cycle.

The transmit sequence begins when the slave device receives the clock signal and the most significant bit of the data on its MOSI pin. The remaining bits (the 7 bits in 8-bit data frame format, and the 15 bits in 16-bit data frame format) are loaded into the shift-register. The TXE flag in the SPI\_SR register is set on the transfer of data from the Tx Buffer to the shift register and an interrupt is generated if the TXEIE bit in the SPI\_CR2 register is set.

### Receive sequence

For the receiver, when data transfer is complete:

- The Data in shift register is transferred to Rx Buffer and the RXNE flag (SPI\_SR register) is set
- An Interrupt is generated if the RXNEIE bit is set in the SPI\_CR2 register.

After the last sampling clock edge the RXNE bit is set, a copy of the data byte received in the shift register is moved to the Rx buffer. When the SPI\_DR register is read, the SPI peripheral returns this buffered value.

Clearing of the RXNE bit is performed by reading the SPI\_DR register.

### SPI TI protocol in slave mode

In slave mode, the SPI interface is compatible with the TI protocol. The FRF bit of the SPI\_CR2 register can be used to configure the slave SPI serial communications to be compliant with this protocol.

The clock polarity and phase are forced to conform to the TI protocol requirements whatever the values set in the SPI\_CR1 register. NSS management is also specific to the TI protocol which makes the configuration of NSS management through the SPI\_CR1 and SPI\_CR2 registers (such as SSM, SSI, SSOE) transparent for the user.

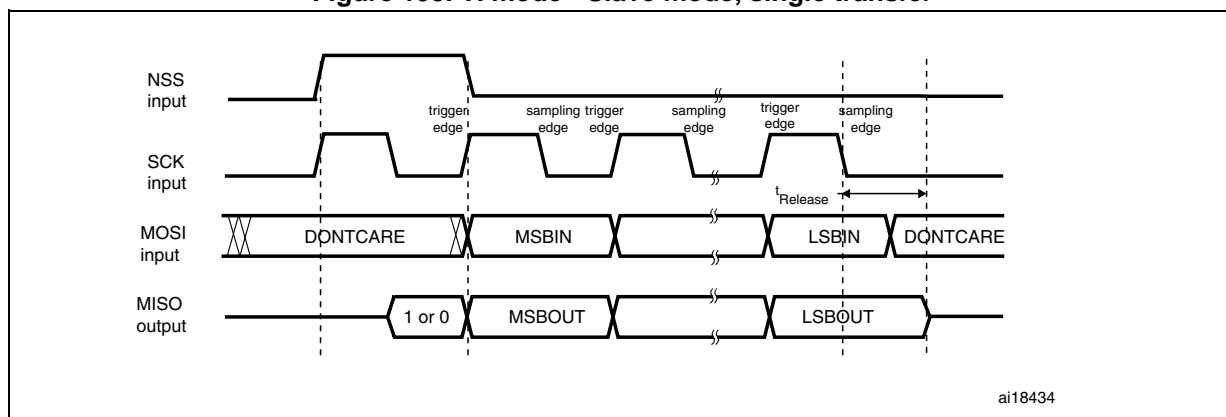
In Slave mode (*Figure 195: TI mode - Slave mode, single transfer* and *Figure 196: TI mode - Slave mode, continuous transfer*), the SPI baud rate prescaler is used to control the moment when the MISO pin state changes to HI-Z. Any baud rate can be used thus allowing to determine this moment with optimal flexibility. However, the baud rate is generally set to the external master clock baud rate. The time for the MISO signal to become HI-Z ( $t_{\text{release}}$ ) depends on internal resynchronizations and on the baud rate value set in through BR[2:0] of SPI\_CR1 register. It is given by the formula:

$$\frac{t_{\text{baud\_rate}}}{2} + 4 \times t_{\text{pclk}} < t_{\text{release}} < \frac{t_{\text{baud\_rate}}}{2} + 6 \times t_{\text{pclk}}$$

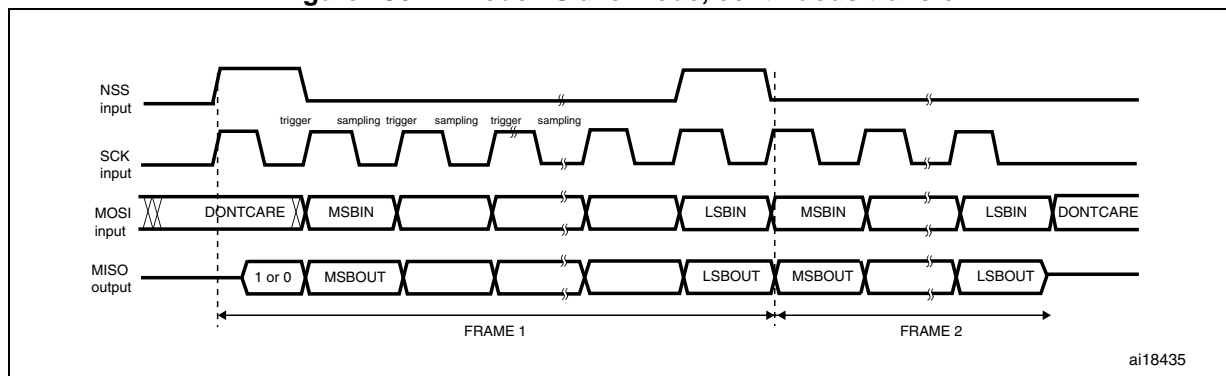
*Note:* This feature is not available for Motorola SPI communications (FRF bit set to 0).

To detect TI frame errors in Slave transmitter only mode by using the Error interrupt (ERRIE = 1), the SPI must be configured in 2-line unidirectional mode by setting BIDIMODE and BIDIOE to 1 in the SPI\_CR1 register. When BIDIMODE is set to 0, OVR is set to 1 because the data register is never read and error interrupt are always generated, while when BIDIMODE is set to 1, data are not received and OVR is never set.

**Figure 195. TI mode - Slave mode, single transfer**



**Figure 196. TI mode - Slave mode, continuous transfer**



### 20.3.3 Configuring the SPI in master mode

In the master configuration, the serial clock is generated on the SCK pin.

#### Procedure

1. Select the BR[2:0] bits to define the serial clock baud rate (see SPI\_CR1 register).
2. Select the CPOL and CPHA bits to define one of the four relationships between the data transfer and the serial clock (see [Figure 194](#)). This step is not required when the TI mode is selected.
3. Set the DFF bit to define 8- or 16-bit data frame format
4. Configure the LSBFIRST bit in the SPI\_CR1 register to define the frame format. This step is not required when the TI mode is selected.
5. If the NSS pin is required in input mode, in hardware mode, connect the NSS pin to a high-level signal during the complete byte transmit sequence. In NSS software mode, set the SSM and SSI bits in the SPI\_CR1 register. If the NSS pin is required in output mode, the SSOE bit only should be set. This step is not required when the TI mode is selected.
6. Set the FRF bit in SPI\_CR2 to select the TI protocol for serial communications.
7. The MSTR and SPE bits must be set (they remain set only if the NSS pin is connected to a high-level signal).

In this configuration the MOSI pin is a data output and the MISO pin is a data input.

#### Transmit sequence

The transmit sequence begins when a byte is written in the Tx Buffer.

The data byte is parallel-loaded into the shift register (from the internal bus) during the first bit transmission and then shifted out serially to the MOSI pin MSB first or LSB first depending on the LSBFIRST bit in the SPI\_CR1 register. The TXE flag is set on the transfer of data from the Tx Buffer to the shift register and an interrupt is generated if the TXEIE bit in the SPI\_CR2 register is set.

#### Receive sequence

For the receiver, when data transfer is complete:

- The data in the shift register is transferred to the RX Buffer and the RXNE flag is set
- An interrupt is generated if the RXNEIE bit is set in the SPI\_CR2 register

At the last sampling clock edge the RXNE bit is set, a copy of the data byte received in the shift register is moved to the Rx buffer. When the SPI\_DR register is read, the SPI peripheral returns this buffered value.

Clearing the RXNE bit is performed by reading the SPI\_DR register.

A continuous transmit stream can be maintained if the next data to be transmitted is put in the Tx buffer once the transmission is started. Note that TXE flag should be '1' before any attempt to write the Tx buffer is made.

*Note:* When a master is communicating with SPI slaves which need to be de-selected between transmissions, the NSS pin must be configured as GPIO or another GPIO must be used and toggled by software.

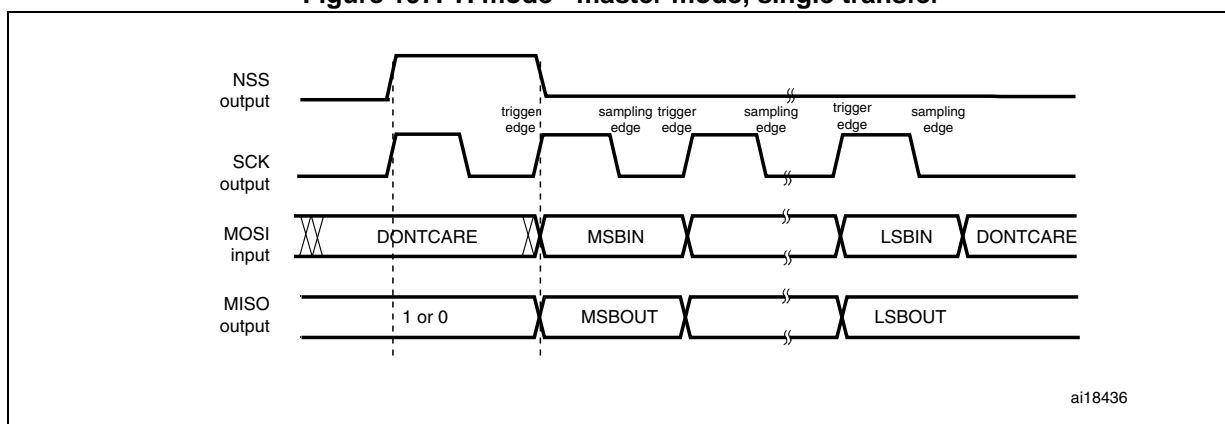
### SPI TI protocol in master mode

In master mode, the SPI interface is compatible with the TI protocol. The FRF bit of the SPI\_CR2 register can be used to configure the master SPI serial communications to be compliant with this protocol.

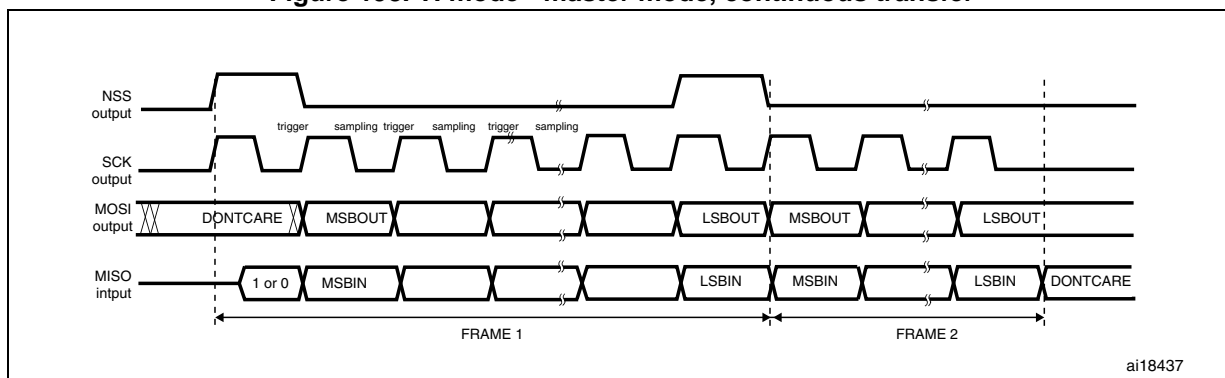
The clock polarity and phase are forced to conform to the TI protocol requirements whatever the values set in the SPI\_CR1 register. NSS management is also specific to the TI protocol which makes the configuration of NSS management through the SPI\_CR1 and SPI\_CR2 registers (SSM, SSI, SSOE) transparent for the user.

*Figure 197: TI mode - master mode, single transfer* and *Figure 198: TI mode - master mode, continuous transfer* show the SPI master communication waveforms when the TI mode is selected in master mode.

**Figure 197. TI mode - master mode, single transfer**



**Figure 198. TI mode - master mode, continuous transfer**





### 20.3.4 Configuring the SPI for half-duplex communication

The SPI is capable of operating in half-duplex mode in 2 configurations.

- 1 clock and 1 bidirectional data wire
- 1 clock and 1 data wire (receive-only or transmit-only)

#### 1 clock and 1 bidirectional data wire (BIDIMODE=1)

This mode is enabled by setting the BIDIMODE bit in the SPI\_CR1 register. In this mode SCK is used for the clock and MOSI in master or MISO in slave mode is used for data communication. The transfer direction (Input/Output) is selected by the BIDIOE bit in the SPI\_CR1 register. When this bit is 1, the data line is output otherwise it is input.

#### 1 clock and 1 unidirectional data wire (BIDIMODE=0)

In this mode, the application can use the SPI either in transmit-only mode or in receive-only mode.

- Transmit-only mode is similar to full-duplex mode (BIDIMODE=0, RXONLY=0): the data are transmitted on the transmit pin (MOSI in master mode or MISO in slave mode) and the receive pin (MISO in master mode or MOSI in slave mode) can be used as a general-purpose IO. In this case, the application just needs to ignore the Rx buffer (if the data register is read, it does not contain the received value).
- In receive-only mode, the application can disable the SPI output function by setting the RXONLY bit in the SPI\_CR2 register. In this case, it frees the transmit IO pin (MOSI in master mode or MISO in slave mode), so it can be used for other purposes.

To start the communication in receive-only mode, configure and enable the SPI:

- In master mode, the communication starts immediately and stops when the SPE bit is cleared and the current reception stops. There is no need to read the BSY flag in this mode. It is always set when an SPI communication is ongoing.
- In slave mode, the SPI continues to receive as long as the NSS is pulled down (or the SSI bit is cleared in NSS software mode) and the SCK is running.

### 20.3.5 Data transmission and reception procedures

#### Rx and Tx buffers

In reception, data are received and then stored into an internal Rx buffer while In transmission, data are first stored into an internal Tx buffer before being transmitted.

A read access of the SPI\_DR register returns the Rx buffered value whereas a write access to the SPI\_DR stores the written data into the Tx buffer.

**Start sequence in master mode**

- In full-duplex (BIDIMODE=0 and RXONLY=0)
  - The sequence begins when data are written into the SPI\_DR register (Tx buffer).
  - The data are then parallel loaded from the Tx buffer into the 8-bit shift register during the first bit transmission and then shifted out serially to the MOSI pin.
  - At the same time, the received data on the MISO pin is shifted in serially to the 8-bit shift register and then parallel loaded into the SPI\_DR register (Rx buffer).
- In unidirectional receive-only mode (BIDIMODE=0 and RXONLY=1)
  - The sequence begins as soon as SPE=1
  - Only the receiver is activated and the received data on the MISO pin are shifted in serially to the 8-bit shift register and then parallel loaded into the SPI\_DR register (Rx buffer).
- In bidirectional mode, when transmitting (BIDIMODE=1 and BIDIOE=1)
  - The sequence begins when data are written into the SPI\_DR register (Tx buffer).
  - The data are then parallel loaded from the Tx buffer into the 8-bit shift register during the first bit transmission and then shifted out serially to the MOSI pin.
  - No data are received.
- In bidirectional mode, when receiving (BIDIMODE=1 and BIDIOE=0)
  - The sequence begins as soon as SPE=1 and BIDIOE=0.
  - The received data on the MOSI pin are shifted in serially to the 8-bit shift register and then parallel loaded into the SPI\_DR register (Rx buffer).
  - The transmitter is not activated and no data are shifted out serially to the MOSI pin.

**Start sequence in slave mode**

- In full-duplex mode (BIDIMODE=0 and RXONLY=0)
  - The sequence begins when the slave device receives the clock signal and the first bit of the data on its MOSI pin. The 7 remaining bits are loaded into the shift register.
  - At the same time, the data are parallel loaded from the Tx buffer into the 8-bit shift register during the first bit transmission, and then shifted out serially to the MISO pin. The software must have written the data to be sent before the SPI master device initiates the transfer.
- In unidirectional receive-only mode (BIDIMODE=0 and RXONLY=1)
  - The sequence begins when the slave device receives the clock signal and the first bit of the data on its MOSI pin. The 7 remaining bits are loaded into the shift register.
  - The transmitter is not activated and no data are shifted out serially to the MISO pin.
- In bidirectional mode, when transmitting (BIDIMODE=1 and BIDIOE=1)
  - The sequence begins when the slave device receives the clock signal and the first bit in the Tx buffer is transmitted on the MISO pin.
  - The data are then parallel loaded from the Tx buffer into the 8-bit shift register during the first bit transmission and then shifted out serially to the MISO pin. The

software must have written the data to be sent before the SPI master device initiates the transfer.

- No data are received.
- In bidirectional mode, when receiving (BIDIMODE=1 and BIDIOE=0)
  - The sequence begins when the slave device receives the clock signal and the first bit of the data on its MISO pin.
  - The received data on the MISO pin are shifted in serially to the 8-bit shift register and then parallel loaded into the SPI\_DR register (Rx buffer).
  - The transmitter is not activated and no data are shifted out serially to the MISO pin.

### Handling data transmission and reception

The TXE flag (Tx buffer empty) is set when the data are transferred from the Tx buffer to the shift register. It indicates that the internal Tx buffer is ready to be loaded with the next data. An interrupt can be generated if the TXEIE bit in the SPI\_CR2 register is set. Clearing the TXE bit is performed by writing to the SPI\_DR register.

*Note:* The software must ensure that the TXE flag is set to 1 before attempting to write to the Tx buffer. Otherwise, it overwrites the data previously written to the Tx buffer.

The RXNE flag (Rx buffer not empty) is set on the last sampling clock edge, when the data are transferred from the shift register to the Rx buffer. It indicates that data are ready to be read from the SPI\_DR register. An interrupt can be generated if the RXNEIE bit in the SPI\_CR2 register is set. Clearing the RXNE bit is performed by reading the SPI\_DR register.

For some configurations, the BSY flag can be used during the last data transfer to wait until the completion of the transfer.

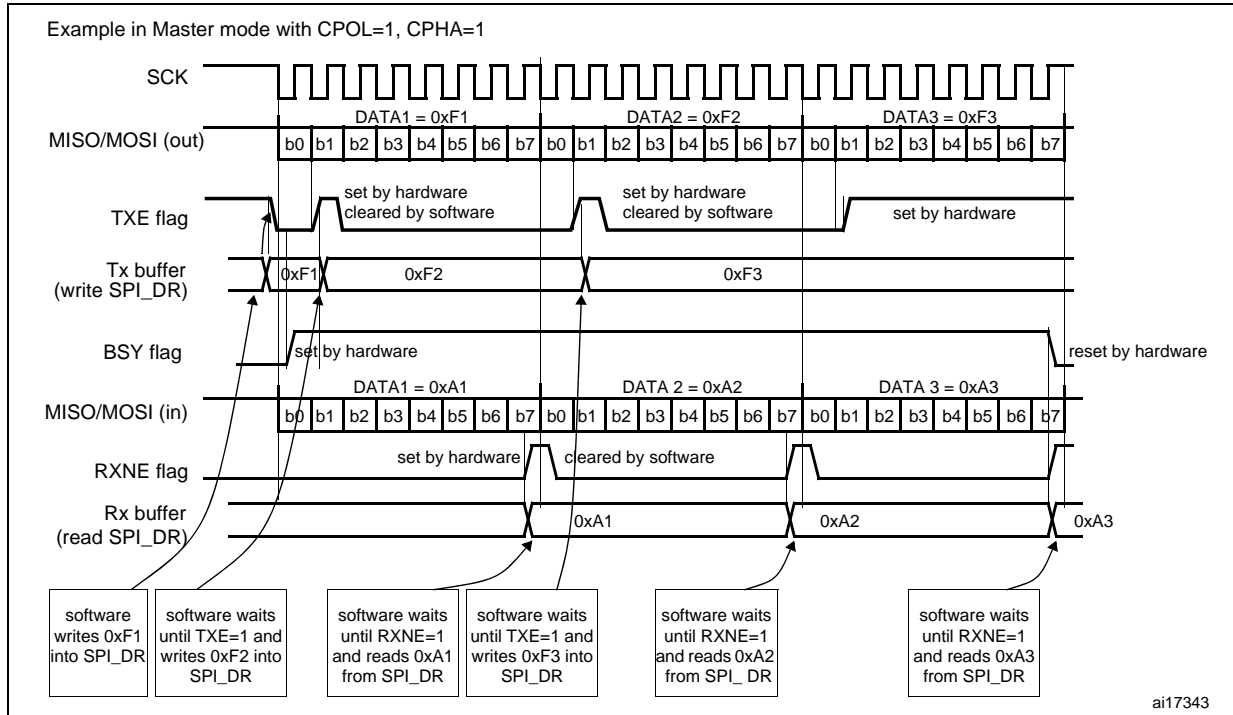
Full-duplex transmit and receive procedure in master or slave mode (BIDIMODE=0 and RXONLY=0)

The software has to follow this procedure to transmit and receive data (see [Figure 199](#) and [Figure 200](#)):

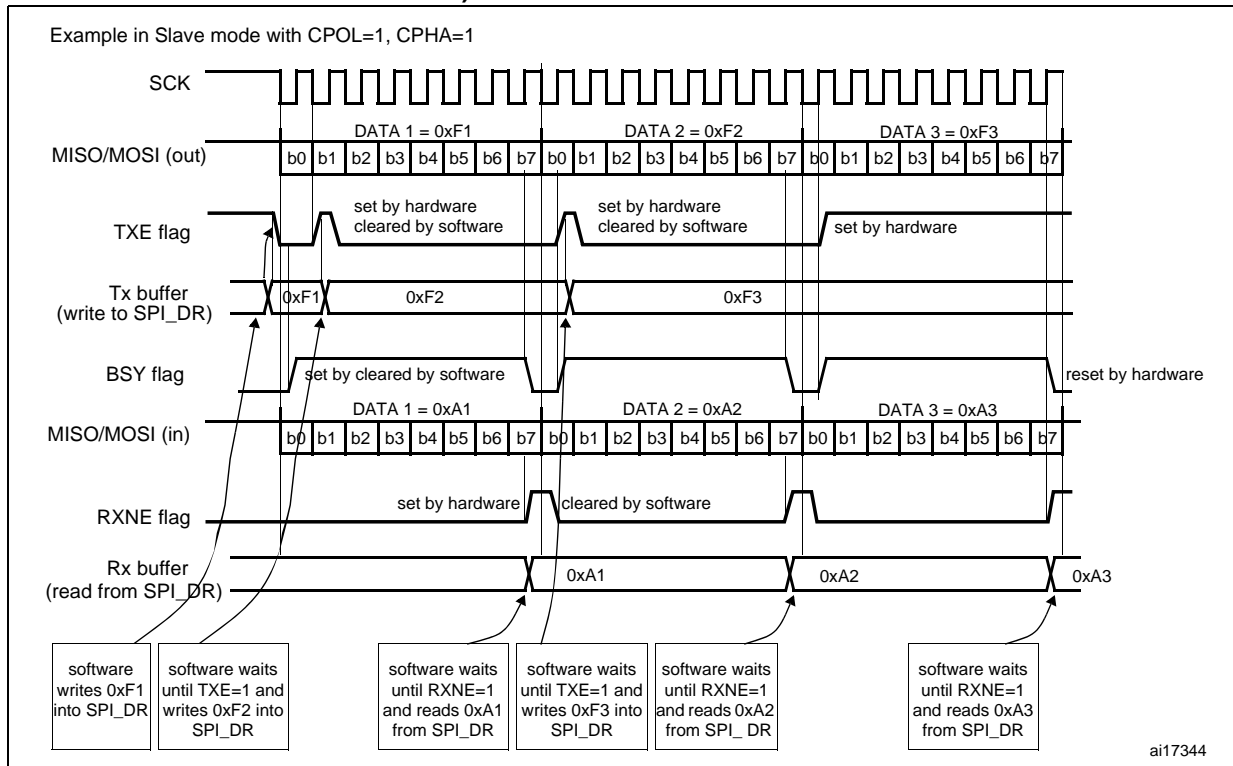
1. Enable the SPI by setting the SPE bit to 1.
2. Write the first data item to be transmitted into the SPI\_DR register (this clears the TXE flag).
3. Wait until TXE=1 and write the second data item to be transmitted. Then wait until RXNE=1 and read the SPI\_DR to get the first received data item (this clears the RXNE bit). Repeat this operation for each data item to be transmitted/received until the n-1 received data.
4. Wait until RXNE=1 and read the last received data.
5. Wait until TXE=1 and then wait until BSY=0 before disabling the SPI.

This procedure can also be implemented using dedicated interrupt subroutines launched at each rising edges of the RXNE or TXE flag.

**Figure 199. TXE/RXNE/BSY behavior in Master / full-duplex mode (BIDIMODE=0 and RXONLY=0) in the case of continuous transfers**



**Figure 200. TXE/RXNE/BSY behavior in Slave / full-duplex mode (BIDIMODE=0, RXONLY=0) in the case of continuous transfers**



**Transmit-only procedure (BIDIMODE=0 RXONLY=0)**

In this mode, the procedure can be reduced as described below and the BSY bit can be used to wait until the completion of the transmission (see *Figure 201* and *Figure 202*).

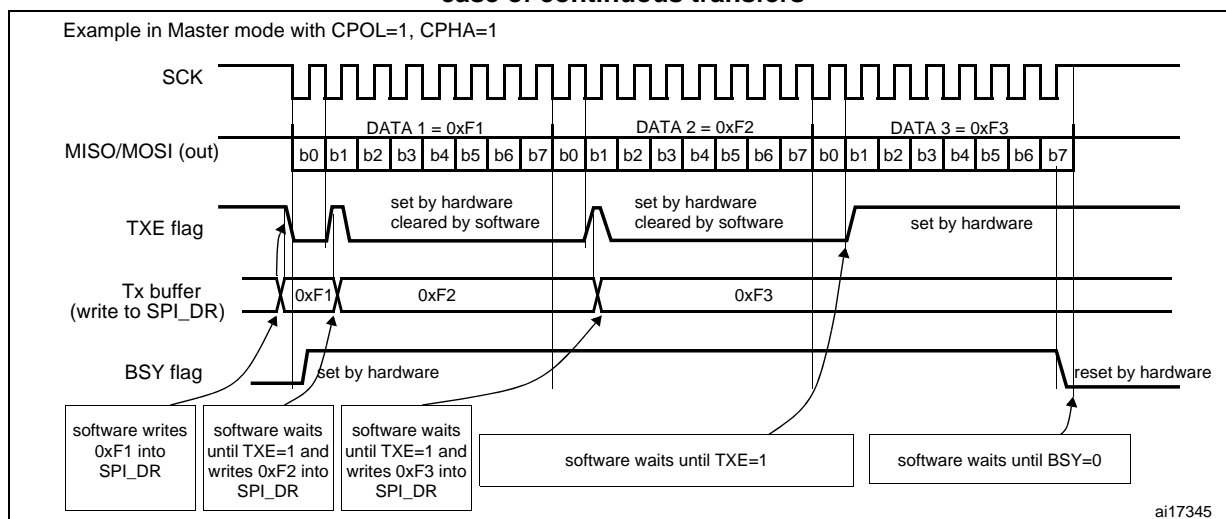
1. Enable the SPI by setting the SPE bit to 1.
2. Write the first data item to send into the SPI\_DR register (this clears the TXE bit).
3. Wait until TXE=1 and write the next data item to be transmitted. Repeat this step for each data item to be transmitted.
4. After writing the last data item into the SPI\_DR register, wait until TXE=1, then wait until BSY=0, this indicates that the transmission of the last data is complete.

This procedure can be also implemented using dedicated interrupt subroutines launched at each rising edge of the TXE flag.

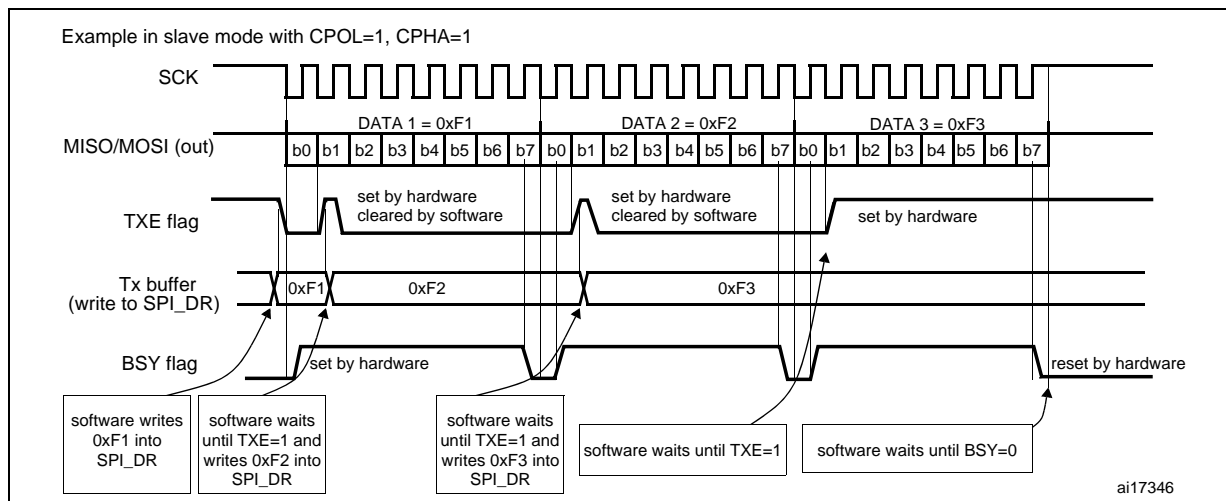
*Note:* During discontinuous communications, there is a 2 APB clock period delay between the write operation to SPI\_DR and the BSY bit setting. As a consequence, in transmit-only mode, it is mandatory to wait first until TXE is set and then until BSY is cleared after writing the last data.

After transmitting two data items in transmit-only mode, the OVR flag is set in the SPI\_SR register since the received data are never read.

**Figure 201. TXE/BSY behavior in Master transmit-only mode (BIDIMODE=0 and RXONLY=0) in case of continuous transfers**



**Figure 202. TXE/BSY in Slave transmit-only mode (BIDIMODE=0 and RXONLY=0) in the case of continuous transfers**



**Bidirectional transmit procedure (BIDIMODE=1 and BIDIOE=1)**

In this mode, the procedure is similar to the procedure in Transmit-only mode except that the BIDIMODE and BIDIOE bits both have to be set in the SPI\_CR2 register before enabling the SPI.

**Unidirectional receive-only procedure (BIDIMODE=0 and RXONLY=1)**

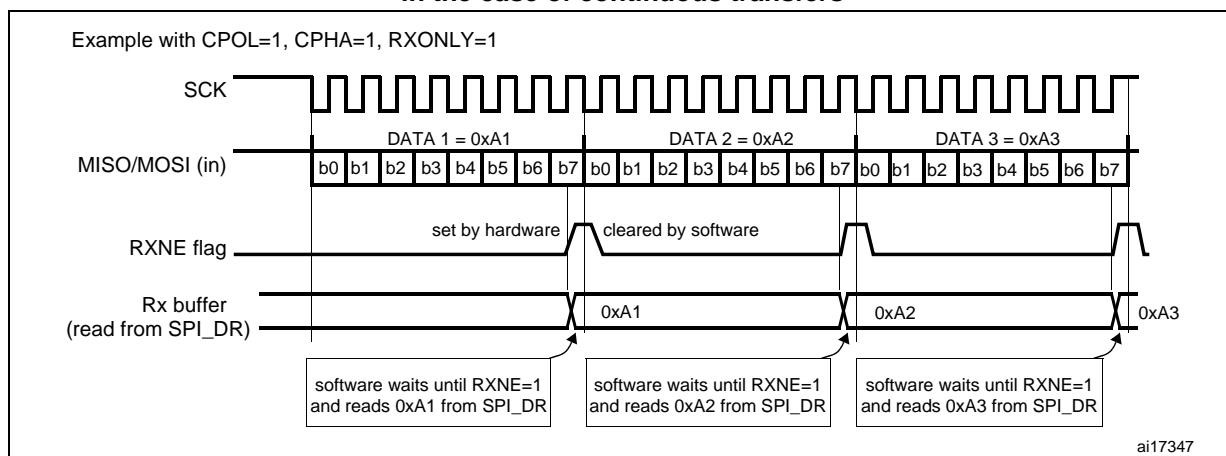
In this mode, the procedure can be reduced as described below (see [Figure 203](#)):

1. Set the RXONLY bit in the SPI\_CR2 register.
2. Enable the SPI by setting the SPE bit to 1:
  - a) In master mode, this immediately activates the generation of the SCK clock, and data are serially received until the SPI is disabled (SPE=0).
  - b) In slave mode, data are received when the SPI master device drives NSS low and generates the SCK clock.
3. Wait until RXNE=1 and read the SPI\_DR register to get the received data (this clears the RXNE bit). Repeat this operation for each data item to be received.

This procedure can also be implemented using dedicated interrupt subroutines launched at each rising edge of the RXNE flag.

*Note:* If it is required to disable the SPI after the last transfer, follow the recommendation described in [Section 20.3.8: Disabling the SPI on page 574](#).

**Figure 203. RXNE behavior in receive-only mode (BIDIRMODE=0 and RXONLY=1) in the case of continuous transfers**



### Bidirectional receive procedure (BIDIMODE=1 and BIDIOE=0)

In this mode, the procedure is similar to the Receive-only mode procedure except that the BIDIMODE bit has to be set and the BIDIOE bit cleared in the SPI\_CR2 register before enabling the SPI.

### Continuous and discontinuous transfers

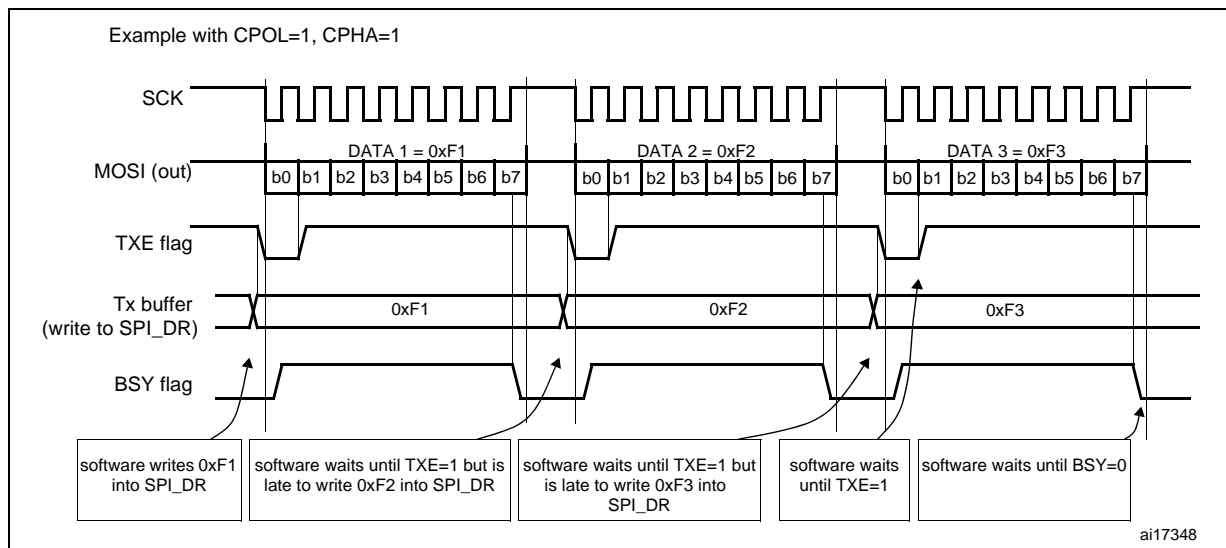
When transmitting data in master mode, if the software is fast enough to detect each rising edge of TXE (or TXE interrupt) and to immediately write to the SPI\_DR register before the ongoing data transfer is complete, the communication is said to be continuous. In this case, there is no discontinuity in the generation of the SPI clock between each data item and the BSY bit is never cleared between each data transfer.

On the contrary, if the software is not fast enough, this can lead to some discontinuities in the communication. In this case, the BSY bit is cleared between each data transmission (see [Figure 204](#)).

In Master receive-only mode (RXONLY=1), the communication is always continuous and the BSY flag is always read at 1.

In slave mode, the continuity of the communication is decided by the SPI master device. In any case, even if the communication is continuous, the BSY flag goes low between each transfer for a minimum duration of one SPI clock cycle (see [Figure 202](#)).

**Figure 204. TXE/BSY behavior when transmitting (BIDIRMODE=0 and RXONLY=0) in the case of discontinuous transfers**



### 20.3.6 CRC calculation

A CRC calculator has been implemented for communication reliability. Separate CRC calculators are implemented for transmitted data and received data. The CRC is calculated using a programmable polynomial serially on each bit. It is calculated on the sampling clock edge defined by the CPHA and CPOL bits in the SPI\_CR1 register.

*Note:* This SPI offers two kinds of CRC calculation standard which depend directly on the data frame format selected for the transmission and/or reception: 8-bit data (CR8) and 16-bit data (CRC16).

CRC calculation is enabled by setting the CRCEN bit in the SPI\_CR1 register. This action resets the CRC registers (SPI\_RXCRCR and SPI\_TXCRCR). In full duplex or transmitter only mode, when the transfers are managed by the software (CPU mode), it is necessary to write the bit CRCNEXT immediately after the last data to be transferred is written to the SPI\_DR. At the end of this last data transfer, the SPI\_TXCRCR value is transmitted.

In receive only mode and when the transfers are managed by software (CPU mode), it is necessary to write the CRCNEXT bit after the second last data has been received. The CRC is received just after the last data reception and the CRC check is then performed.

At the end of data and CRC transfers, the CRCERR flag in the SPI\_SR register is set if corruption occurs during the transfer.

If data are present in the TX buffer, the CRC value is transmitted only after the transmission of the data byte. During CRC transmission, the CRC calculator is switched off and the register value remains unchanged.

SPI communication using the CRC is possible through the following procedure:



1. Program the CPOL, CPHA, LSBFirst, BR, SSM, SSI and MSTR values.
2. Program the polynomial in the SPI\_CRCPR register.
3. Enable the CRC calculation by setting the CRCEN bit in the SPI\_CR1 register. This also clears the SPI\_RXCR and SPI\_TXCR registers.
4. Enable the SPI by setting the SPE bit in the SPI\_CR1 register.
5. Start the communication and sustain the communication until all but one byte or half-word have been transmitted or received.
  - In full duplex or transmitter-only mode, when the transfers are managed by software, when writing the last byte or half word to the Tx buffer, set the CRCNEXT bit in the SPI\_CR1 register to indicate that the CRC will be transmitted after the transmission of the last byte.
  - In receiver only mode, set the bit CRCNEXT just after the reception of the second to last data to prepare the SPI to enter in CRC Phase at the end of the reception of the last data. CRC calculation is frozen during the CRC transfer.
6. After the transfer of the last byte or half word, the SPI enters the CRC transfer and check phase. In full duplex mode or receiver-only mode, the received CRC is compared to the SPI\_RXCR value. If the value does not match, the CRCERR flag in SPI\_SR is set and an interrupt can be generated when the ERRIE bit in the SPI\_CR2 register is set.

*Note:* When the SPI is in slave mode, be careful to enable CRC calculation only when the clock is stable, that is, when the clock is in the steady state. If not, a wrong CRC calculation may be done. In fact, the CRC is sensitive to the SCK slave input clock as soon as CRCEN is set, and this, whatever the value of the SPE bit.

*With high bitrate frequencies, be careful when transmitting the CRC. As the number of used CPU cycles has to be as low as possible in the CRC transfer phase, it is forbidden to call software functions in the CRC transmission sequence to avoid errors in the last data and CRC reception. In fact, CRCNEXT bit has to be written before the end of the transmission/reception of the last data.*

*For high bit rate frequencies, it is advised to use the DMA mode to avoid the degradation of the SPI speed performance due to CPU accesses impacting the SPI bandwidth.*

*When the devices are configured as slaves and the NSS hardware mode is used, the NSS pin needs to be kept low between the data phase and the CRC phase.*

When the SPI is configured in slave mode with the CRC feature enabled, CRC calculation takes place even if a high level is applied on the NSS pin. This may happen for example in case of a multislave environment where the communication master addresses slaves alternately.

Between a slave deselection (high level on NSS) and a new slave selection (low level on NSS), the CRC value should be cleared on both master and slave sides in order to resynchronize the master and slave for their respective CRC calculation.

To clear the CRC, follow the procedure below:

1. Disable SPI (SPE = 0)
2. Clear the CRCEN bit
3. Set the CRCEN bit
4. Enable the SPI (SPE = 1)

### 20.3.7 Status flags

Four status flags are provided for the application to completely monitor the state of the SPI bus.

#### Tx buffer empty flag (TXE)

When it is set, this flag indicates that the Tx buffer is empty and the next data to be transmitted can be loaded into the buffer. The TXE flag is cleared when writing to the SPI\_DR register.

#### Rx buffer not empty (RXNE)

When set, this flag indicates that there are valid received data in the Rx buffer. It is cleared when SPI\_DR is read.

#### BUSY flag

This BSY flag is set and cleared by hardware (writing to this flag has no effect). The BSY flag indicates the state of the communication layer of the SPI.

When BSY is set, it indicates that the SPI is busy communicating. There is one exception in master mode / bidirectional receive mode (MSTR=1 and BDM=1 and BDOE=0) where the BSY flag is kept low during reception.

The BSY flag is useful to detect the end of a transfer if the software wants to disable the SPI and enter Halt mode (or disable the peripheral clock). This avoids corrupting the last transfer. For this, the procedure described below must be strictly respected.

The BSY flag is also useful to avoid write collisions in a multimaster system.

The BSY flag is set when a transfer starts, with the exception of master mode / bidirectional receive mode (MSTR=1 and BDM=1 and BDOE=0).

It is cleared:

- when a transfer is finished (except in master mode if the communication is continuous)
- when the SPI is disabled
- when a master mode fault occurs (MODF=1)

When communication is not continuous, the BSY flag is low between each communication.

When communication is continuous:

- in master mode, the BSY flag is kept high during all the transfers
- in slave mode, the BSY flag goes low for one SPI clock cycle between each transfer

*Note:* Do not use the BSY flag to handle each data transmission or reception. It is better to use the TXE and RXNE flags instead.

### 20.3.8 Disabling the SPI

When a transfer is terminated, the application can stop the communication by disabling the SPI peripheral. This is done by clearing the SPE bit.

For some configurations, disabling the SPI and entering the Halt mode while a transfer is ongoing can cause the current transfer to be corrupted and/or the BSY flag might become unreliable.

To avoid any of those effects, it is recommended to respect the following procedure when disabling the SPI:

#### **In master or slave full-duplex mode (BIDIMODE=0, RXONLY=0)**

1. Wait until RXNE=1 to receive the last data
2. Wait until TXE=1
3. Then wait until BSY=0
4. Disable the SPI (SPE=0) and, eventually, enter the Halt mode (or disable the peripheral clock)

#### **In master or slave unidirectional transmit-only mode (BIDIMODE=0, RXONLY=0) or bidirectional transmit mode (BIDIMODE=1, BIDIOE=1)**

After the last data is written into the SPI\_DR register:

1. Wait until TXE=1
2. Then wait until BSY=0
3. Disable the SPI (SPE=0) and, eventually, enter the Halt mode (or disable the peripheral clock)

#### **In master unidirectional receive-only mode (MSTR=1, BIDIMODE=0, RXONLY=1) or bidirectional receive mode (MSTR=1, BIDIMODE=1, BIDIOE=0)**

This case must be managed in a particular way to ensure that the SPI does not initiate a new transfer. The sequence below is valid only for SPI Motorola configuration (FRF bit set to 0):

1. Wait for the second to last occurrence of RXNE=1 (n-1)
2. Then wait for one SPI clock cycle (using a software loop) before disabling the SPI (SPE=0)
3. Then wait for the last RXNE=1 before entering the Halt mode (or disabling the peripheral clock)

When the SPI is configured in TI mode (Bit FRF set to 1), the following procedure has to be respected to avoid generating an undesired pulse on NSS when the SPI is disabled:

1. Wait for the second to last occurrence of RXNE = 1 (n-1).
2. Disable the SPI (SPE = 0) in the following window frame using a software loop:
  - After at least one SPI clock cycle,
  - Before the beginning of the LSB data transfer.

*Note:* In master bidirectional receive mode (MSTR=1 and BDM=1 and BDOE=0), the BSY flag is kept low during transfers.

**In slave receive-only mode (MSTR=0, BIDIMODE=0, RXONLY=1) or bidirectional receive mode (MSTR=0, BIDIMODE=1, BIDOE=0)**

1. You can disable the SPI (write SPE=1) at any time: the current transfer will complete before the SPI is effectively disabled
2. Then, if you want to enter the Halt mode, you must first wait until BSY = 0 before entering the Halt mode (or disabling the peripheral clock).

**20.3.9 SPI communication using DMA (direct memory addressing)**

To operate at its maximum speed, the SPI needs to be fed with the data for transmission and the data received on the Rx buffer should be read to avoid overrun. To facilitate the transfers, the SPI features a DMA capability implementing a simple request/acknowledge protocol.

A DMA access is requested when the enable bit in the SPI\_CR2 register is enabled. Separate requests must be issued to the Tx and Rx buffers (see [Figure 205](#) and [Figure 206](#)):

- In transmission, a DMA request is issued each time TXE is set to 1. The DMA then writes to the SPI\_DR register (this clears the TXE flag).
- In reception, a DMA request is issued each time RXNE is set to 1. The DMA then reads the SPI\_DR register (this clears the RXNE flag).

When the SPI is used only to transmit data, it is possible to enable only the SPI Tx DMA channel. In this case, the OVR flag is set because the data received are not read.

When the SPI is used only to receive data, it is possible to enable only the SPI Rx DMA channel.

In transmission mode, when the DMA has written all the data to be transmitted (flag TCIF is set in the DMA\_ISR register), the BSY flag can be monitored to ensure that the SPI communication is complete. This is required to avoid corrupting the last transmission before disabling the SPI or entering the Stop mode. The software must first wait until TXE=1 and then until BSY=0.

*Note:* During discontinuous communications, there is a 2 APB clock period delay between the write operation to SPI\_DR and the BSY bit setting. As a consequence, it is mandatory to wait first until TXE=1 and then until BSY=0 after writing the last data.

Figure 205. Transmission using DMA

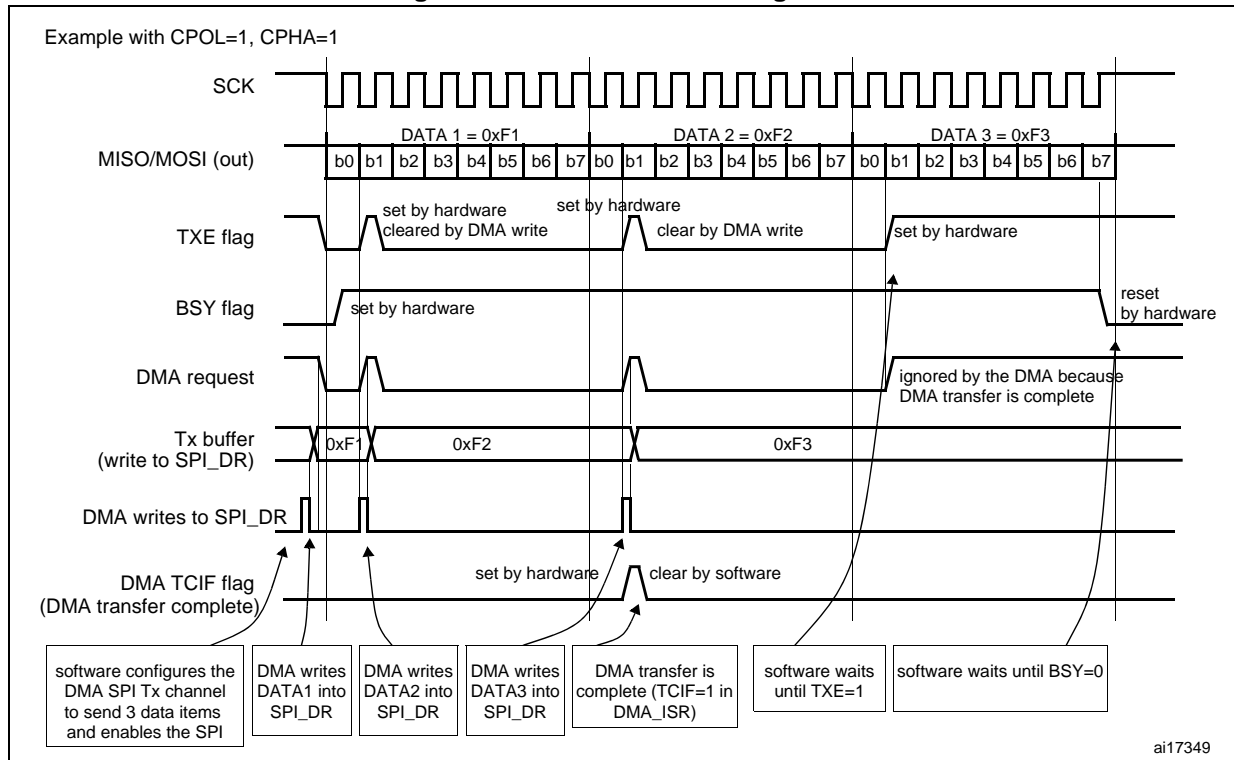
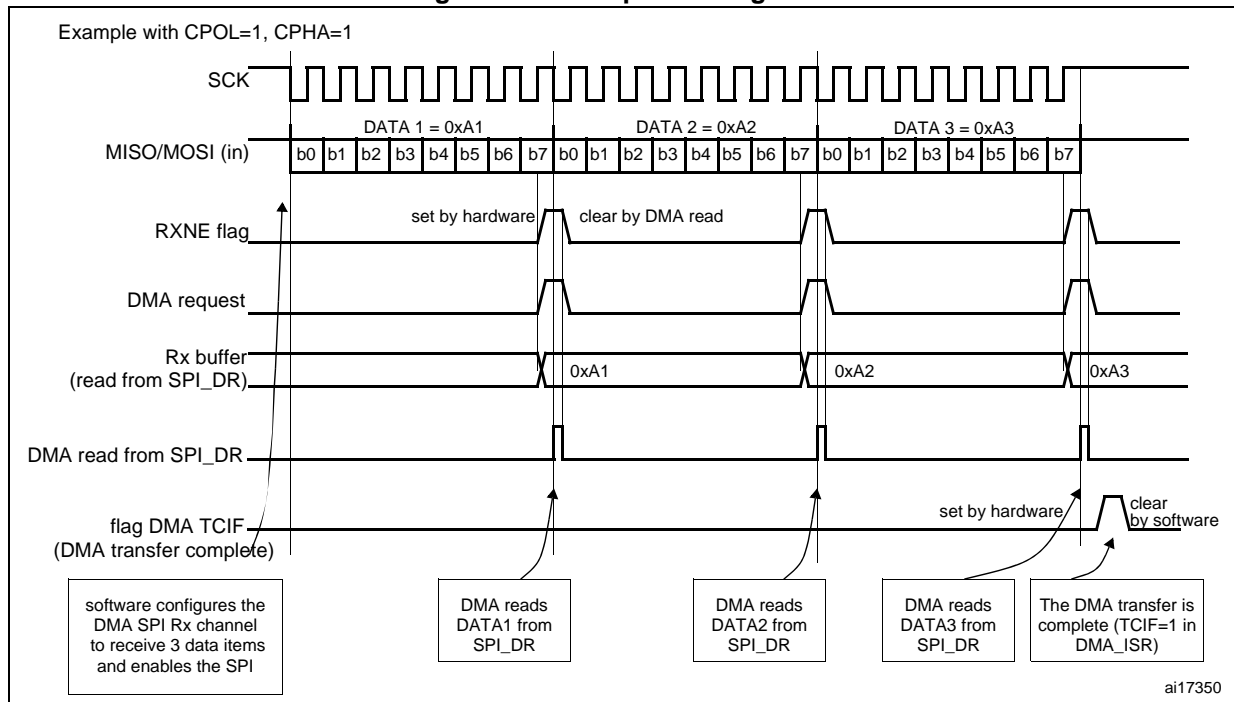


Figure 206. Reception using DMA



### DMA capability with CRC

When SPI communication is enabled with CRC communication and DMA mode, the transmission and reception of the CRC at the end of communication are automatic that is without using the bit CRCNEXT. After the CRC reception, the CRC must be read in the SPI\_DR register to clear the RXNE flag.

At the end of data and CRC transfers, the CRCERR flag in SPI\_SR is set if corruption occurs during the transfer.

## 20.3.10 Error flags

### Master mode fault (MODF)

Master mode fault occurs when the master device has its NSS pin pulled low (in NSS hardware mode) or SSI bit low (in NSS software mode), this automatically sets the MODF bit. Master mode fault affects the SPI peripheral in the following ways:

- The MODF bit is set and an SPI interrupt is generated if the ERRIE bit is set.
- The SPE bit is cleared. This blocks all output from the device and disables the SPI interface.
- The MSTR bit is cleared, thus forcing the device into slave mode.

Use the following software sequence to clear the MODF bit:

1. Make a read or write access to the SPI\_SR register while the MODF bit is set.
2. Then write to the SPI\_CR1 register.

To avoid any multiple slave conflicts in a system comprising several MCUs, the NSS pin must be pulled high during the MODF bit clearing sequence. The SPE and MSTR bits can be restored to their original state after this clearing sequence.

As a security, hardware does not allow the setting of the SPE and MSTR bits while the MODF bit is set.

In a slave device the MODF bit cannot be set. However, in a multimaster configuration, the device can be in slave mode with this MODF bit set. In this case, the MODF bit indicates that there might have been a multimaster conflict for system control. An interrupt routine can be used to recover cleanly from this state by performing a reset or returning to a default state.

### Overrun condition

An overrun condition occurs when the master device has sent data bytes and the slave device has not cleared the RXNE bit resulting from the previous data byte transmitted.

When an overrun condition occurs:

- the OVR bit is set and an interrupt is generated if the ERRIE bit is set.

In this case, the receiver buffer contents will not be updated with the newly received data from the master device. A read from the SPI\_DR register returns this byte. All other subsequently transmitted bytes are lost.

Clearing the OVR bit is done by a read from the SPI\_DR register followed by a read access to the SPI\_SR register.

### CRC error

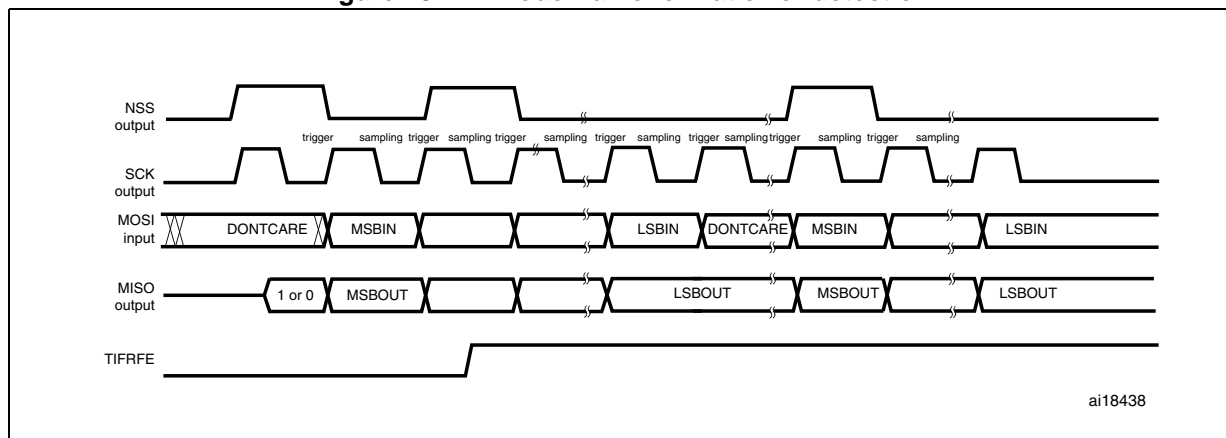
This flag is used to verify the validity of the value received when the CRCEN bit in the SPI\_CR1 register is set. The CRCERR flag in the SPI\_SR register is set if the value received in the shift register does not match the receiver SPI\_RXCRCR value.

### TI mode frame format error

A TI mode frame format error is detected when an NSS pulse occurs during an ongoing communication when the SPI is acting in slave mode and configured to conform to the TI mode protocol. When this error occurs, the FRE flag is set in the SPI\_SR register. The SPI is not disabled when an error occurs, the NSS pulse is ignored, and the SPI waits for the next NSS pulse before starting a new transfer. The data may be corrupted since the error detection may result in the lost of two data bytes.

The FRE flag is cleared when SPI\_SR register is read. If the bit ERRIE is set, an interrupt is generated on the NSS error detection. In this case, the SPI should be disabled because data consistency is no more guaranteed and communications should be reinitiated by the master when the slave SPI is re-enabled.

Figure 207. TI mode frame format error detection



## 20.3.11 SPI interrupts

Table 90. SPI interrupt requests

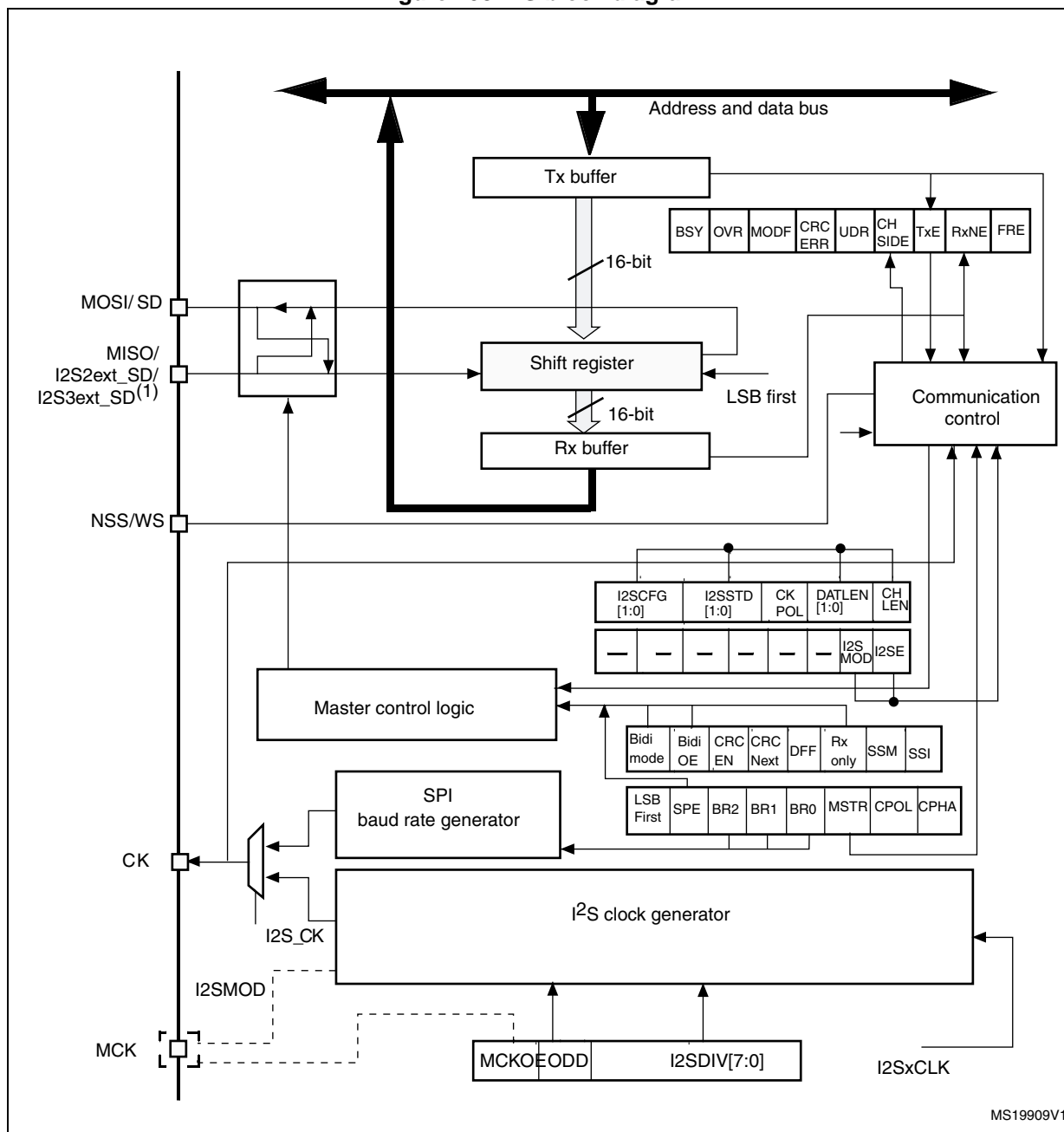
Interrupt event	Event flag	Enable Control bit
Transmit buffer empty flag	TXE	TXEIE
Receive buffer not empty flag	RXNE	RXNEIE
Master Mode fault event	MODF	ERRIE
Overrun error	OVR	
CRC error flag	CRCERR	
TI frame format error	FRE	

## 20.4 I<sup>2</sup>S functional description

### 20.4.1 I<sup>2</sup>S general description

The block diagram of the I<sup>2</sup>S is shown in [Figure 208](#).

Figure 208. I<sup>2</sup>S block diagram



1. I2S2ext\_SD and I2S3ext\_SD are the extended SD pins that control the I<sup>2</sup>S full duplex mode.

The SPI could function as an audio I<sup>2</sup>S interface when the I<sup>2</sup>S capability is enabled (by setting the I2SMOD bit in the SPI\_I2SCFGR register). This interface uses almost the same pins, flags and interrupts as the SPI.



The I<sup>2</sup>S shares three common pins with the SPI:

- SD: Serial Data (mapped on the MOSI pin) to transmit or receive the two time-multiplexed data channels (in half-duplex mode only).
- WS: Word Select (mapped on the NSS pin) is the data control signal output in master mode and input in slave mode.
- CK: Serial Clock (mapped on the SCK pin) is the serial clock output in master mode and serial clock input in slave mode.
- I2S2ext\_SD and I2S3ext\_SD: additional pins (mapped on the MISO pin) to control the I<sup>2</sup>S full duplex mode.

An additional pin could be used when a master clock output is needed for some external audio devices:

- MCK: Master Clock (mapped separately) is used, when the I<sup>2</sup>S is configured in master mode (and when the MCKOE bit in the SPI\_I2SPR register is set), to output this additional clock generated at a preconfigured frequency rate equal to  $256 \times F_S$ , where  $F_S$  is the audio sampling frequency.

The I<sup>2</sup>S uses its own clock generator to produce the communication clock when it is set in master mode. This clock generator is also the source of the master clock output. Two additional registers are available in I<sup>2</sup>S mode. One is linked to the clock generator configuration SPI\_I2SPR and the other one is a generic I<sup>2</sup>S configuration register SPI\_I2SCFGR (audio standard, slave/master mode, data format, packet frame, clock polarity, etc.).

The SPI\_CR1 register and all CRC registers are not used in the I<sup>2</sup>S mode. Likewise, the SSOE bit in the SPI\_CR2 register and the MODF and CRCERR bits in the SPI\_SR are not used.

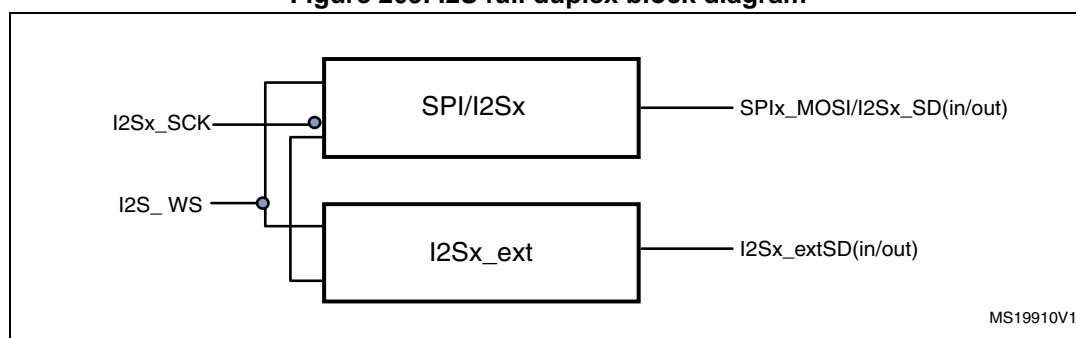
The I<sup>2</sup>S uses the same SPI register for data transfer (SPI\_DR) in 16-bit wide mode.

### 20.4.2 I2S full duplex

To support I2S full duplex mode, two extra I<sup>2</sup>S instances called extended I2Ss (I2S2\_ext, I2S3\_ext) are available in addition to I2S2 and I2S3 (see [Figure 209](#)). The first I2S full-duplex interface is consequently based on I2S2 and I2S2\_ext, and the second one on I2S3 and I2S3\_ext.

*Note:* I2S2\_ext and I2S3\_ext are used only in full-duplex mode.

**Figure 209. I2S full duplex block diagram**



1. Where x can be 2 or 3.

I2Sx can operate in master mode. As a result:

- Only I2Sx can output SCK and WS in half duplex mode
- Only I2Sx can deliver SCK and WS to I2S2\_ext and I2S3\_ext in full duplex mode.

The extended I2Ss (I2Sx\_ext) can be used only in full duplex mode. The I2Sx\_ext operate always in slave mode.

Both I2Sx and I2Sx\_ext can be configured as transmitters or receivers.

### 20.4.3 Supported audio protocols

The four-line bus has to handle only audio data generally time-multiplexed on two channels: the right channel and the left channel. However there is only one 16-bit register for the transmission and the reception. So, it is up to the software to write into the data register the adequate value corresponding to the considered channel side, or to read the data from the data register and to identify the corresponding channel by checking the CHSIDE bit in the SPI\_SR register. Channel Left is always sent first followed by the channel right (CHSIDE has no meaning for the PCM protocol).

Four data and packet frames are available. Data may be sent with a format of:

- 16-bit data packed in 16-bit frame
- 16-bit data packed in 32-bit frame
- 24-bit data packed in 32-bit frame
- 32-bit data packed in 32-bit frame

When using 16-bit data extended on 32-bit packet, the first 16 bits (MSB) are the significant bits, the 16-bit LSB is forced to 0 without any need for software action or DMA request (only one read/write operation).

The 24-bit and 32-bit data frames need two CPU read or write operations to/from the SPI\_DR or two DMA operations if the DMA is preferred for the application. For 24-bit data frame specifically, the 8 nonsignificant bits are extended to 32 bits with 0-bits (by hardware).

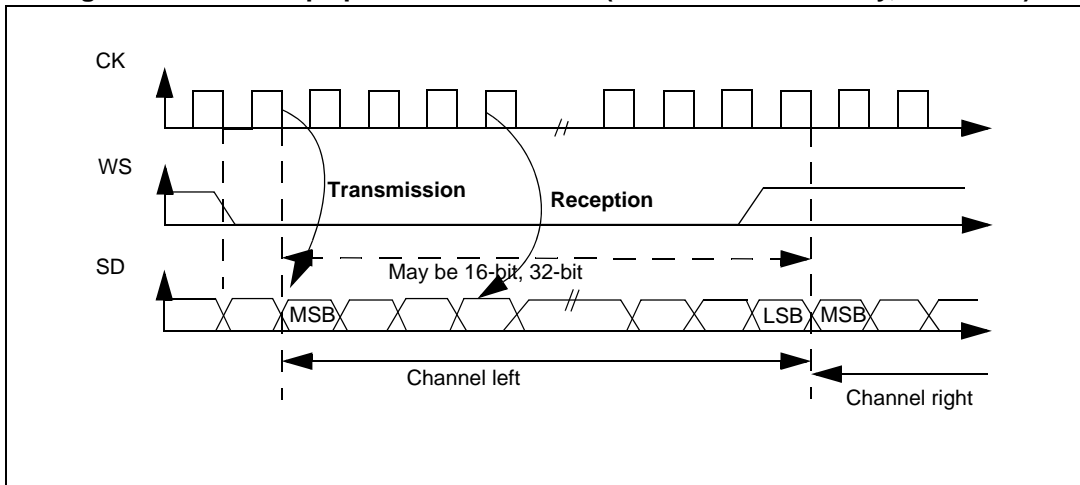
For all data formats and communication standards, the most significant bit is always sent first (MSB first).

The I<sup>2</sup>S interface supports four audio standards, configurable using the I2SSTD[1:0] and PCMSYNC bits in the SPI\_I2SCFGR register.

#### I<sup>2</sup>S Philips standard

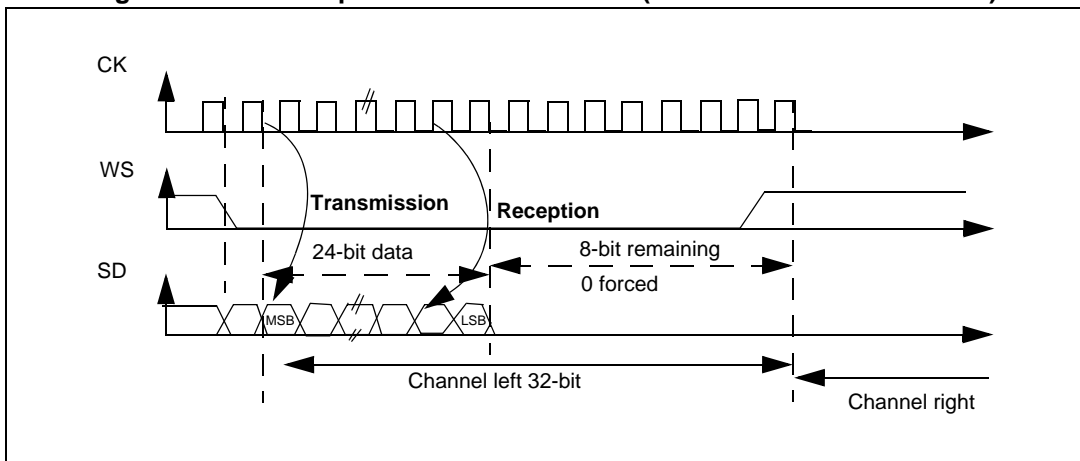
For this standard, the WS signal is used to indicate which channel is being transmitted. It is activated one CK clock cycle before the first bit (MSB) is available.

Figure 210. I<sup>2</sup>S Philips protocol waveforms (16/32-bit full accuracy, CPOL = 0)



Data are latched on the falling edge of CK (for the transmitter) and are read on the rising edge (for the receiver). The WS signal is also latched on the falling edge of CK.

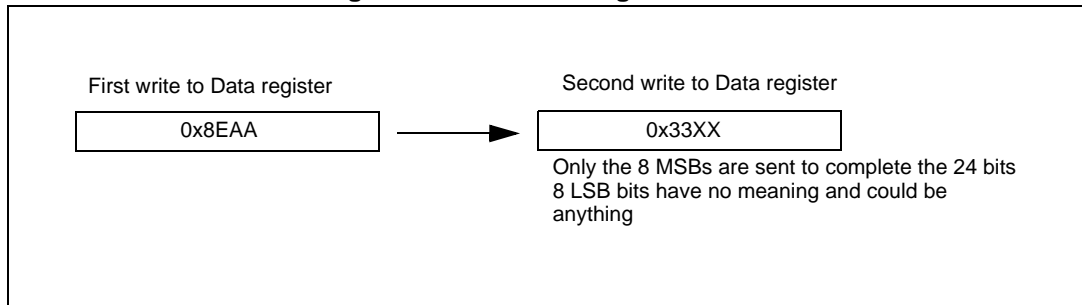
Figure 211. I<sup>2</sup>S Philips standard waveforms (24-bit frame with CPOL = 0)



This mode needs two write or read operations to/from the SPI\_DR.

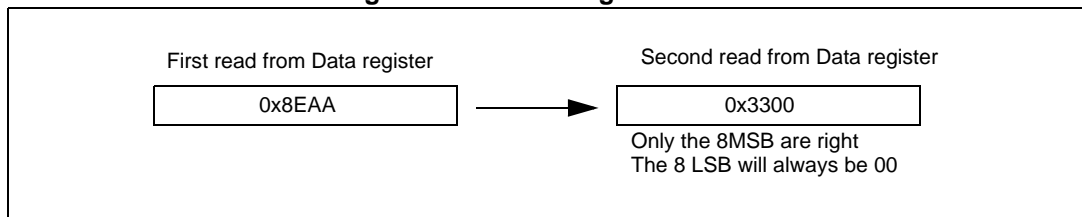
- In transmission mode:  
if 0x8EAA33 has to be sent (24-bit):

**Figure 212. Transmitting 0x8EAA33**

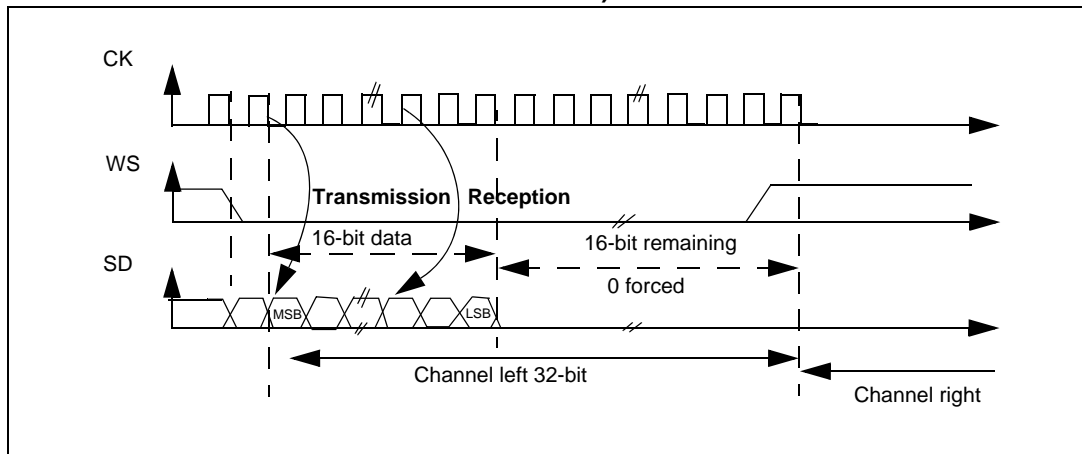


- In reception mode:  
if data 0x8EAA33 is received:

**Figure 213. Receiving 0x8EAA33**



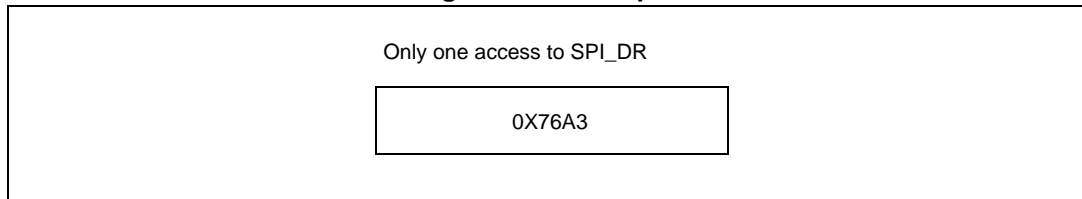
**Figure 214. I<sup>2</sup>S Philips standard (16-bit extended to 32-bit packet frame with CPOL = 0)**



When 16-bit data frame extended to 32-bit channel frame is selected during the I<sup>2</sup>S configuration phase, only one access to SPI\_DR is required. The 16 remaining bits are forced by hardware to 0x0000 to extend the data to 32-bit format.

If the data to transmit or the received data are 0x76A3 (0x76A30000 extended to 32-bit), the operation shown in [Figure 215](#) is required.

Figure 215. Example



For transmission, each time an MSB is written to SPI\_DR, the TXE flag is set and its interrupt, if allowed, is generated to load SPI\_DR with the new value to send. This takes place even if 0x0000 have not yet been sent because it is done by hardware.

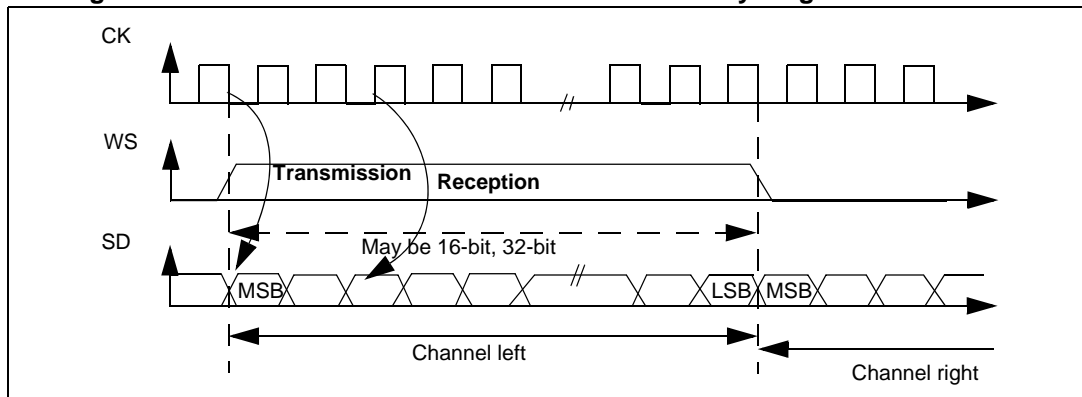
For reception, the RXNE flag is set and its interrupt, if allowed, is generated when the first 16 MSB half-word is received.

In this way, more time is provided between two write or read operations, which prevents underrun or overrun conditions (depending on the direction of the data transfer).

**MSB justified standard**

For this standard, the WS signal is generated at the same time as the first data bit, which is the MSBit.

Figure 216. MSB Justified 16-bit or 32-bit full-accuracy length with CPOL = 0



Data are latched on the falling edge of CK (for transmitter) and are read on the rising edge (for the receiver).

Figure 217. MSB Justified 24-bit frame length with CPOL = 0

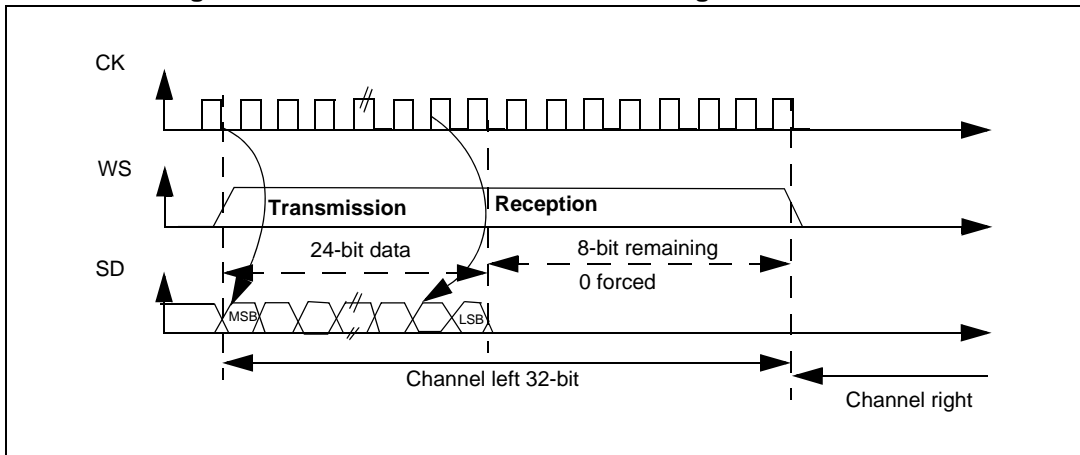
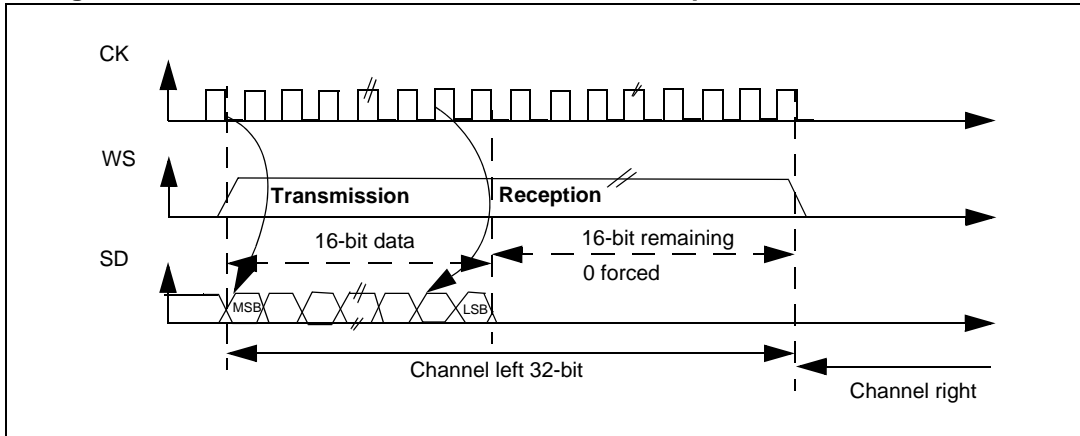


Figure 218. MSB Justified 16-bit extended to 32-bit packet frame with CPOL = 0



**LSB justified standard**

This standard is similar to the MSB justified standard (no difference for the 16-bit and 32-bit full-accuracy frame formats).

Figure 219. LSB justified 16-bit or 32-bit full-accuracy with CPOL = 0

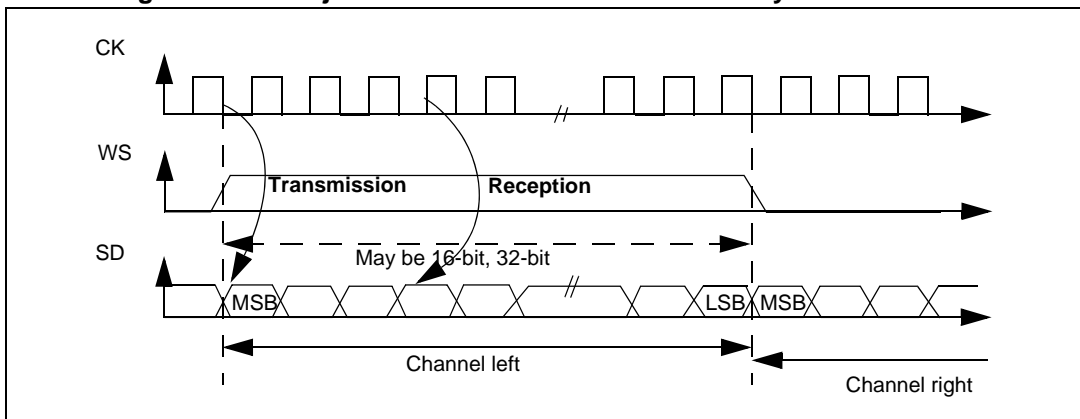
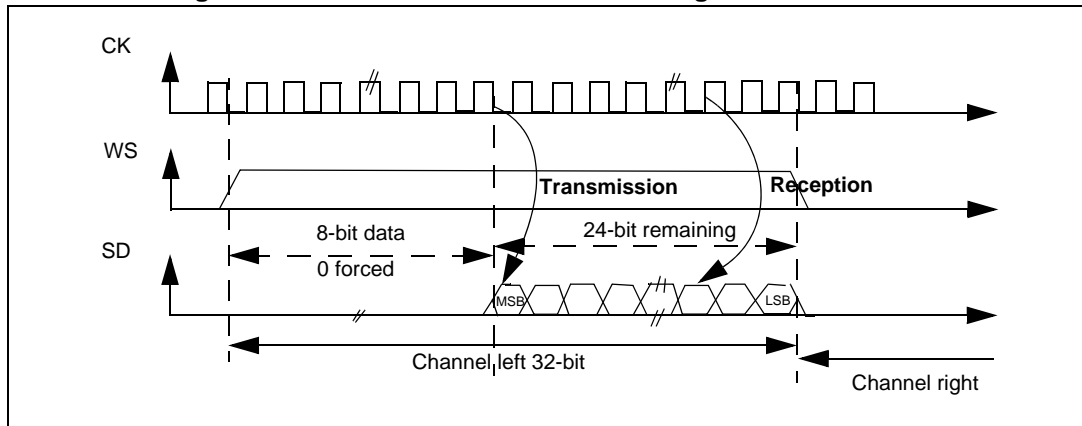
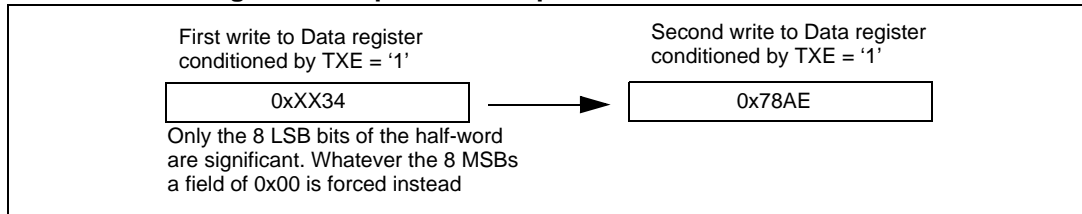


Figure 220. LSB Justified 24-bit frame length with CPOL = 0



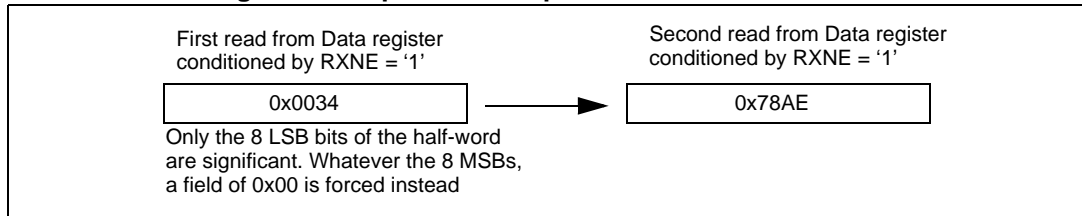
- In transmission mode:  
If data 0x3478AE have to be transmitted, two write operations to the SPI\_DR register are required from software or by DMA. The operations are shown below.

Figure 221. Operations required to transmit 0x3478AE

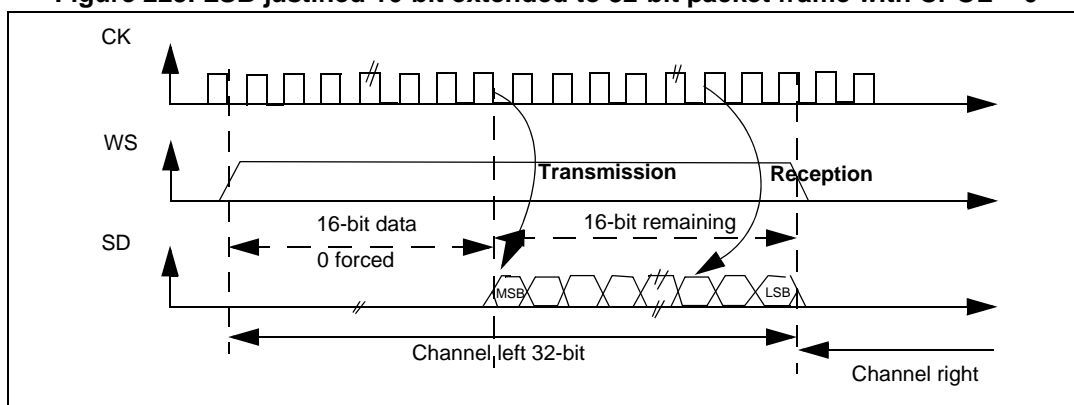


- In reception mode:  
If data 0x3478AE are received, two successive read operations from SPI\_DR are required on each RXNE event.

Figure 222. Operations required to receive 0x3478AE



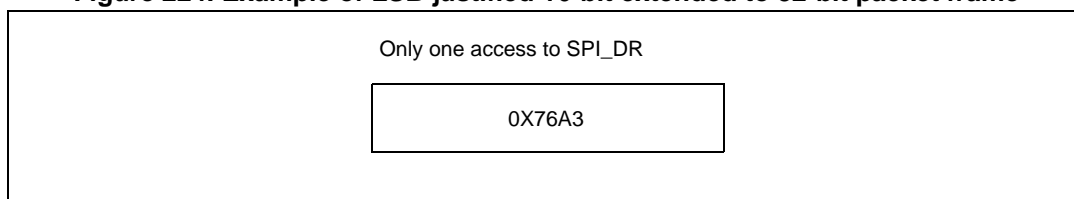
**Figure 223. LSB justified 16-bit extended to 32-bit packet frame with CPOL = 0**



When 16-bit data frame extended to 32-bit channel frame is selected during the I<sup>2</sup>S configuration phase, Only one access to SPI\_DR is required. The 16 remaining bits are forced by hardware to 0x0000 to extend the data to 32-bit format. In this case it corresponds to the half-word MSB.

If the data to transmit or the received data are 0x76A3 (0x0000 76A3 extended to 32-bit), the operation shown in [Figure 224](#) is required.

**Figure 224. Example of LSB justified 16-bit extended to 32-bit packet frame**



In transmission mode, when TXE is asserted, the application has to write the data to be transmitted (in this case 0x76A3). The 0x000 field is transmitted first (extension on 32-bit). TXE is asserted again as soon as the effective data (0x76A3) is sent on SD.

In reception mode, RXNE is asserted as soon as the significant half-word is received (and not the 0x0000 field).

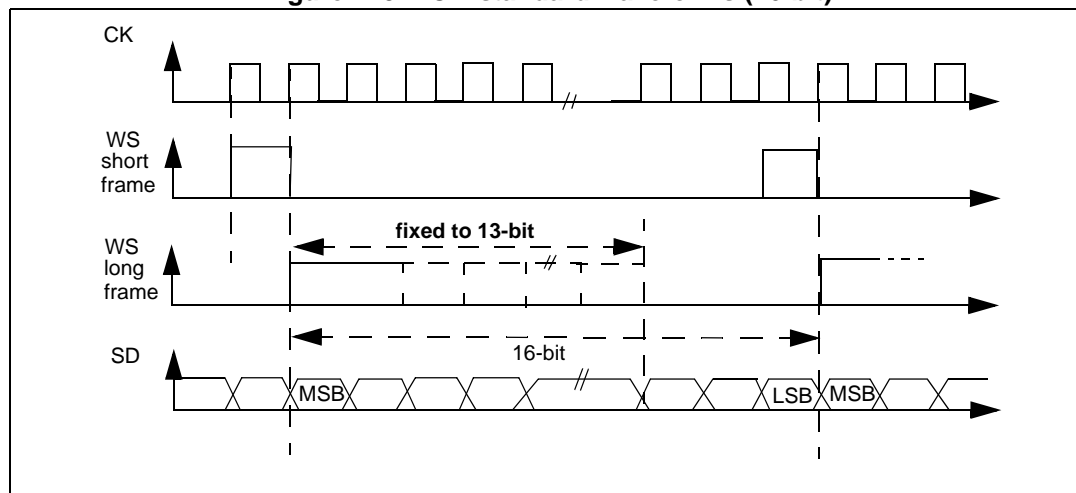
In this way, more time is provided between two write or read operations to prevent underrun or overrun conditions.



**PCM standard**

For the PCM standard, there is no need to use channel-side information. The two PCM modes (short and long frame) are available and configurable using the PCMSYNC bit in SPI\_I2SCFGR.

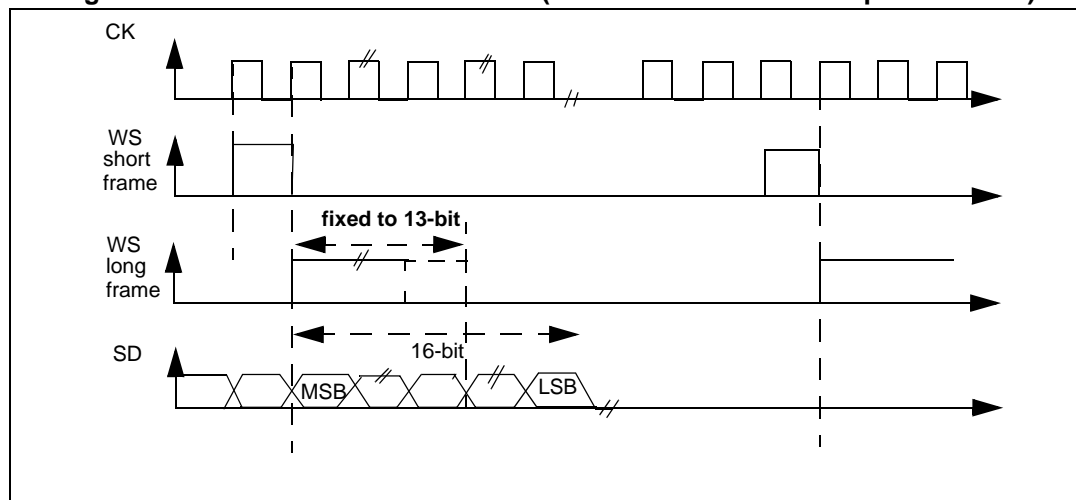
**Figure 225. PCM standard waveforms (16-bit)**



For long frame synchronization, the WS signal assertion time is fixed 13 bits in master mode.

For short frame synchronization, the WS synchronization signal is only one cycle long.

**Figure 226. PCM standard waveforms (16-bit extended to 32-bit packet frame)**



*Note:* For both modes (master and slave) and for both synchronizations (short and long), the number of bits between two consecutive pieces of data (and so two synchronization signals) needs to be specified (DATLEN and CHLEN bits in the SPI\_I2SCFGR register) even in slave mode.

### 20.4.4 Clock generator

The I<sup>2</sup>S bitrate determines the dataflow on the I<sup>2</sup>S data line and the I<sup>2</sup>S clock signal frequency.

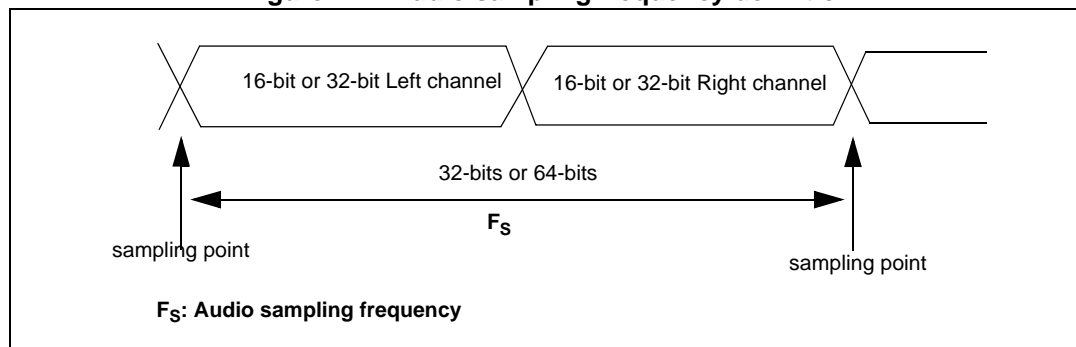
I<sup>2</sup>S bitrate = number of bits per channel x number of channels x sampling audio frequency

For a 16-bit audio, left and right channel, the I<sup>2</sup>S bitrate is calculated as follows:

$$I^2S \text{ bitrate} = 16 \times 2 \times F_S$$

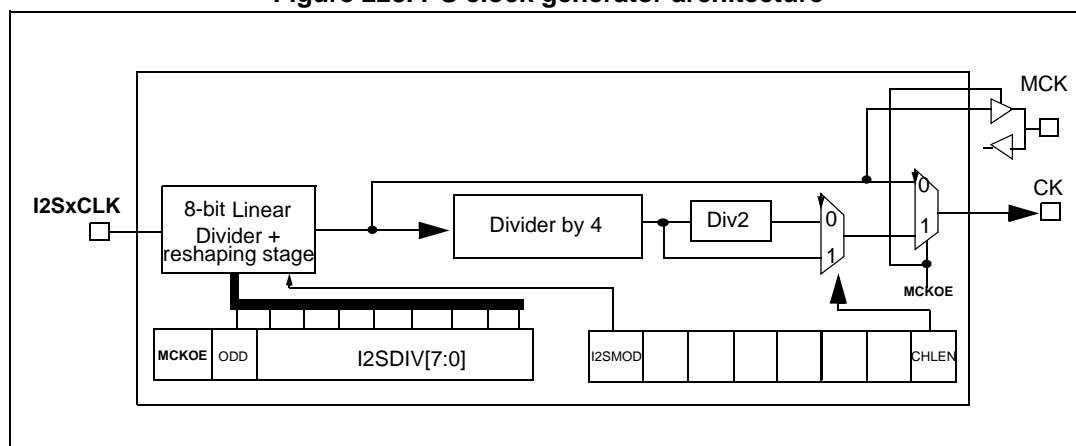
It will be: I<sup>2</sup>S bitrate = 32 x 2 x F<sub>S</sub> if the packet length is 32-bit wide.

**Figure 227. Audio sampling frequency definition**



When the master mode is configured, a specific action needs to be taken to properly program the linear divider in order to communicate with the desired audio frequency.

**Figure 228. I<sup>2</sup>S clock generator architecture**



1. Where x could be 2 or 3.

Figure 227 presents the communication clock architecture. To achieve high-quality audio performance, the I2SxCLK clock source can be either the PLLI2S output (through R division factor) or an external clock (mapped to I2S\_CKIN pin).

The audio sampling frequency can be 192 kHz, 96 kHz, or 48 kHz. In order to reach the desired frequency, the linear divider needs to be programmed according to the formulas below:

When the master clock is generated (MCKOE in the SPI\_I2SPR register is set):

$$F_S = I2SxCLK / [(16 \times 2) \times ((2 \times I2SDIV) + ODD) \times 8]$$

when the channel frame is 16-bit wide

$$F_S = I2SxCLK / [(32 \times 2) \times ((2 \times I2SDIV) + ODD) \times 4]$$

when the channel frame is 32-bit wide

When the master clock is disabled (MCKOE bit cleared):

$$F_S = I2SxCLK / [(16 \cdot 2) \cdot ((2 \cdot I2SDIV) + ODD)]$$
 when the channel frame is 16-bit wide

$$F_S = I2SxCLK / [(32 \cdot 2) \cdot ((2 \cdot I2SDIV) + ODD)]$$
 when the channel frame is 32-bit wide

Table 91 provides example precision values for different clock configurations.

Note: Other configurations are possible that allow optimum clock precision.

**Table 91. Audio frequency precision (for PLLM VCO = 1 MHz or 2 MHz)<sup>(1)</sup>**

Master clock	Target f <sub>S</sub> (Hz)	Data format	PLLI2SN	PLLI2SR	I2SDIV	I2SODD	Real f <sub>S</sub> (Hz)	Error
Disabled	8000	16-bit	192	2	187	1	8000	0.0000%
		32-bit	192	3	62	1	8000	0.0000%
	16000	16-bit	192	3	62	1	16000	0.0000%
		32-bit	256	2	62	1	16000	0.0000%
	32000	16-bit	256	2	62	1	32000	0.0000%
		32-bit	256	5	12	1	32000	0.0000%
	48000	16-bit	192	5	12	1	48000	0.0000%
		32-bit	384	5	12	1	48000	0.0000%
	96000	16-bit	384	5	12	1	96000	0.0000%
		32-bit	424	3	11	1	96014.49219	0.0151%
	22050	16-bit	290	3	68	1	22049.87695	0.0006%
		32-bit	302	2	53	1	22050.23438	0.0011%
	44100	16-bit	302	2	53	1	44100.46875	0.0011%
		32-bit	429	4	19	0	44099.50781	0.0011%
192000	16-bit	424	3	11	1	192028.9844	0.0151%	
	32-bit	258	3	3	1	191964.2813	0.0186%	
Enabled	8000	don't care	256	5	12	1	8000	0.0000%
	16000	don't care	213	2	13	0	16000.60059	0.0038%
	32000	don't care	213	2	6	1	32001.20117	0.0038%
	48000	don't care	258	3	3	1	47991.07031	0.0186%
	96000	don't care	344	2	3	1	95982.14063	0.0186%
	22050	don't care	429	4	9	1	22049.75391	0.0011%
	44100	don't care	271	2	6	0	44108.07422	0.0183%

1. This table gives only example values for different clock configurations. Other configurations allowing optimum clock precision are possible.



### 20.4.5 I<sup>2</sup>S master mode

The I<sup>2</sup>S can be configured as follows:

- In master mode for transmission or reception (half-duplex mode using I2Sx)
- In master mode transmission and reception (full duplex mode using I2Sx and I2Sx\_ext).

This means that the serial clock is generated on the CK pin as well as the Word Select signal WS. Master clock (MCK) may be output or not, thanks to the MCKOE bit in the SPI\_I2SPR register.

#### Procedure

1. Select the I2SDIV[7:0] bits in the SPI\_I2SPR register to define the serial clock baud rate to reach the proper audio sample frequency. The ODD bit in the SPI\_I2SPR register also has to be defined.
2. Select the CKPOL bit to define the steady level for the communication clock. Set the MCKOE bit in the SPI\_I2SPR register if the master clock MCK needs to be provided to the external DAC/ADC audio component (the I2SDIV and ODD values should be computed depending on the state of the MCK output, for more details refer to [Section 20.4.4: Clock generator](#)).
3. Set the I2SMOD bit in SPI\_I2SCFGR to activate the I<sup>2</sup>S functionalities and choose the I<sup>2</sup>S standard through the I2SSTD[1:0] and PCMSYNC bits, the data length through the DATLEN[1:0] bits and the number of bits per channel by configuring the CHLEN bit. Select also the I<sup>2</sup>S master mode and direction (Transmitter or Receiver) through the I2SCFG[1:0] bits in the SPI\_I2SCFGR register.
4. If needed, select all the potential interruption sources and the DMA capabilities by writing the SPI\_CR2 register.
5. The I2SE bit in SPI\_I2SCFGR register must be set.

WS and CK are configured in output mode. MCK is also an output, if the MCKOE bit in SPI\_I2SPR is set.

#### Transmission sequence

The transmission sequence begins when a half-word is written into the Tx buffer.

Assumedly, the first data written into the Tx buffer correspond to the channel Left data. When data are transferred from the Tx buffer to the shift register, TXE is set and data corresponding to the channel Right have to be written into the Tx buffer. The CHSIDE flag indicates which channel is to be transmitted. It has a meaning when the TXE flag is set because the CHSIDE flag is updated when TXE goes high.

A full frame has to be considered as a Left channel data transmission followed by a Right channel data transmission. It is not possible to have a partial frame where only the left channel is sent.

The data half-word is parallel loaded into the 16-bit shift register during the first bit transmission, and then shifted out, serially, to the MOSI/SD pin, MSB first. The TXE flag is set after each transfer from the Tx buffer to the shift register and an interrupt is generated if the TXEIE bit in the SPI\_CR2 register is set.

For more details about the write operations depending on the I<sup>2</sup>S standard mode selected, refer to [Section 20.4.3: Supported audio protocols](#).

To ensure a continuous audio data transmission, it is mandatory to write the SPI\_DR with the next data to transmit before the end of the current transmission.

To switch off the I<sup>2</sup>S, by clearing I2SE, it is mandatory to wait for TXE = 1 and BSY = 0.

### Reception sequence

The operating mode is the same as for the transmission mode except for the point 3 (refer to the procedure described in [Section 20.4.5: I2S master mode](#)), where the configuration should set the master reception mode through the I2SCFG[1:0] bits.

Whatever the data or channel length, the audio data are received by 16-bit packets. This means that each time the Rx buffer is full, the RXNE flag is set and an interrupt is generated if the RXNEIE bit is set in SPI\_CR2 register. Depending on the data and channel length configuration, the audio value received for a right or left channel may result from one or two receptions into the Rx buffer.

Clearing the RXNE bit is performed by reading the SPI\_DR register.

CHSIDE is updated after each reception. It is sensitive to the WS signal generated by the I<sup>2</sup>S cell.

For more details about the read operations depending on the I<sup>2</sup>S standard mode selected, refer to [Section 20.4.3: Supported audio protocols](#).

If data are received while the previously received data have not been read yet, an overrun is generated and the OVR flag is set. If the ERRIE bit is set in the SPI\_CR2 register, an interrupt is generated to indicate the error.

To switch off the I<sup>2</sup>S, specific actions are required to ensure that the I<sup>2</sup>S completes the transfer cycle properly without initiating a new data transfer. The sequence depends on the configuration of the data and channel lengths, and on the audio protocol mode selected. In the case of:

- 16-bit data length extended on 32-bit channel length (DATLEN = 00 and CHLEN = 1) using the LSB justified mode (I2SSTD = 10)
  - a) Wait for the second to last RXNE = 1 (n – 1)
  - b) Then wait 17 I<sup>2</sup>S clock cycles (using a software loop)
  - c) Disable the I<sup>2</sup>S (I2SE = 0)
- 16-bit data length extended on 32-bit channel length (DATLEN = 00 and CHLEN = 1) in MSB justified, I<sup>2</sup>S or PCM modes (I2SSTD = 00, I2SSTD = 01 or I2SSTD = 11, respectively)
  - a) Wait for the last RXNE
  - b) Then wait 1 I<sup>2</sup>S clock cycle (using a software loop)
  - c) Disable the I<sup>2</sup>S (I2SE = 0)
- For all other combinations of DATLEN and CHLEN, whatever the audio mode selected through the I2SSTD bits, carry out the following sequence to switch off the I<sup>2</sup>S:
  - a) Wait for the second to last RXNE = 1 (n – 1)
  - b) Then wait one I<sup>2</sup>S clock cycle (using a software loop)
  - c) Disable the I<sup>2</sup>S (I2SE = 0)

*Note:* The BSY flag is kept low during transfers.

## 20.4.6 I<sup>2</sup>S slave mode

The I<sup>2</sup>S can be configured as follows:

- In slave mode for transmission or reception (half-duplex mode using I2Sx)
- In slave mode transmission and reception (full duplex mode using I2Sx and I2Sx\_ext).

The operating mode is following mainly the same rules as described for the I<sup>2</sup>S master configuration. In slave mode, there is no clock to be generated by the I<sup>2</sup>S interface. The clock and WS signals are input from the external master connected to the I<sup>2</sup>S interface. There is then no need, for the user, to configure the clock.

The configuration steps to follow are listed below:

1. Set the I2SMOD bit in the SPI\_I2SCFGR register to reach the I<sup>2</sup>S functionalities and choose the I<sup>2</sup>S standard through the I2SSTD[1:0] bits, the data length through the DATLEN[1:0] bits and the number of bits per channel for the frame configuring the CHLEN bit. Select also the mode (transmission or reception) for the slave through the I2SCFG[1:0] bits in SPI\_I2SCFGR register.
2. If needed, select all the potential interrupt sources and the DMA capabilities by writing the SPI\_CR2 register.
3. The I2SE bit in SPI\_I2SCFGR register must be set.

### Transmission sequence

The transmission sequence begins when the external master device sends the clock and when the NSS\_WS signal requests the transfer of data. The slave has to be enabled before the external master starts the communication. The I<sup>2</sup>S data register has to be loaded before the master initiates the communication.

For the I<sup>2</sup>S, MSB justified and LSB justified modes, the first data item to be written into the data register corresponds to the data for the left channel. When the communication starts, the data are transferred from the Tx buffer to the shift register. The TXE flag is then set in order to request the right channel data to be written into the I<sup>2</sup>S data register.

The CHSIDE flag indicates which channel is to be transmitted. Compared to the master transmission mode, in slave mode, CHSIDE is sensitive to the WS signal coming from the external master. This means that the slave needs to be ready to transmit the first data before the clock is generated by the master. WS assertion corresponds to left channel transmitted first.

*Note:* The I2SE has to be written at least two PCLK cycles before the first clock of the master comes on the CK line.

The data half-word is parallel-loaded into the 16-bit shift register (from the internal bus) during the first bit transmission, and then shifted out serially to the MOSI/SD pin MSB first. The TXE flag is set after each transfer from the Tx buffer to the shift register and an interrupt is generated if the TXEIE bit in the SPI\_CR2 register is set.

Note that the TXE flag should be checked to be at 1 before attempting to write the Tx buffer.

For more details about the write operations depending on the I<sup>2</sup>S standard mode selected, refer to [Section 20.4.3: Supported audio protocols](#).

To secure a continuous audio data transmission, it is mandatory to write the SPI\_DR register with the next data to transmit before the end of the current transmission. An underrun flag is set and an interrupt may be generated if the data are not written into the SPI\_DR register before the first clock edge of the next data communication. This indicates

to the software that the transferred data are wrong. If the ERRIE bit is set into the SPI\_CR2 register, an interrupt is generated when the UDR flag in the SPI\_SR register goes high. In this case, it is mandatory to switch off the I<sup>2</sup>S and to restart a data transfer starting from the left channel.

To switch off the I<sup>2</sup>S, by clearing the I2SE bit, it is mandatory to wait for TXE = 1 and BSY = 0.

### Reception sequence

The operating mode is the same as for the transmission mode except for the point 1 (refer to the procedure described in [Section 20.4.6: I2S slave mode](#)), where the configuration should set the master reception mode using the I2SCFG[1:0] bits in the SPI\_I2SCFGR register.

Whatever the data length or the channel length, the audio data are received by 16-bit packets. This means that each time the RX buffer is full, the RXNE flag in the SPI\_SR register is set and an interrupt is generated if the RXNEIE bit is set in the SPI\_CR2 register. Depending on the data length and channel length configuration, the audio value received for a right or left channel may result from one or two receptions into the RX buffer.

The CHSIDE flag is updated each time data are received to be read from SPI\_DR. It is sensitive to the external WS line managed by the external master component.

Clearing the RXNE bit is performed by reading the SPI\_DR register.

For more details about the read operations depending the I<sup>2</sup>S standard mode selected, refer to [Section 20.4.3: Supported audio protocols](#).

If data are received while the precedent received data have not yet been read, an overrun is generated and the OVR flag is set. If the bit ERRIE is set in the SPI\_CR2 register, an interrupt is generated to indicate the error.

To switch off the I<sup>2</sup>S in reception mode, I2SE has to be cleared immediately after receiving the last RXNE = 1.

*Note:* The external master components should have the capability of sending/receiving data in 16-bit or 32-bit packets via an audio channel.

## 20.4.7 Status flags

Three status flags are provided for the application to fully monitor the state of the I<sup>2</sup>S bus.

### Busy flag (BSY)

The BSY flag is set and cleared by hardware (writing to this flag has no effect). It indicates the state of the communication layer of the I<sup>2</sup>S.

When BSY is set, it indicates that the I<sup>2</sup>S is busy communicating. There is one exception in master receive mode (I2SCFG = 11) where the BSY flag is kept low during reception.

The BSY flag is useful to detect the end of a transfer if the software needs to disable the I<sup>2</sup>S. This avoids corrupting the last transfer. For this, the procedure described below must be strictly respected.

The BSY flag is set when a transfer starts, except when the I<sup>2</sup>S is in master receiver mode.

The BSY flag is cleared:

- when a transfer completes (except in master transmit mode, in which the communication is supposed to be continuous)
- when the I<sup>2</sup>S is disabled

When communication is continuous:

- In master transmit mode, the BSY flag is kept high during all the transfers
- In slave mode, the BSY flag goes low for one I<sup>2</sup>S clock cycle between each transfer

*Note: Do not use the BSY flag to handle each data transmission or reception. It is better to use the TXE and RXNE flags instead.*

### **Tx buffer empty flag (TXE)**

When set, this flag indicates that the Tx buffer is empty and the next data to be transmitted can then be loaded into it. The TXE flag is reset when the Tx buffer already contains data to be transmitted. It is also reset when the I<sup>2</sup>S is disabled (I2SE bit is reset).

### **RX buffer not empty (RXNE)**

When set, this flag indicates that there are valid received data in the RX Buffer. It is reset when SPI\_DR register is read.

### **Channel Side flag (CHSIDE)**

In transmission mode, this flag is refreshed when TXE goes high. It indicates the channel side to which the data to transfer on SD has to belong. In case of an underrun error event in slave transmission mode, this flag is not reliable and I<sup>2</sup>S needs to be switched off and switched on before resuming the communication.

In reception mode, this flag is refreshed when data are received into SPI\_DR. It indicates from which channel side data have been received. Note that in case of error (like OVR) this flag becomes meaningless and the I<sup>2</sup>S should be reset by disabling and then enabling it (with configuration if it needs changing).

This flag has no meaning in the PCM standard (for both Short and Long frame modes).

When the OVR or UDR flag in the SPI\_SR is set and the ERRIE bit in SPI\_CR2 is also set, an interrupt is generated. This interrupt can be cleared by reading the SPI\_SR status register (once the interrupt source has been cleared).

## **20.4.8 Error flags**

There are three error flags for the I<sup>2</sup>S cell.

### **Underrun flag (UDR)**

In slave transmission mode this flag is set when the first clock for data transmission appears while the software has not yet loaded any value into SPI\_DR. It is available when the I2SMOD bit in SPI\_I2SCFGR is set. An interrupt may be generated if the ERRIE bit in SPI\_CR2 is set.

The UDR bit is cleared by a read operation on the SPI\_SR register.



**Overrun flag (OVR)**

This flag is set when data are received and the previous data have not yet been read from SPI\_DR. As a result, the incoming data are lost. An interrupt may be generated if the ERRIE bit is set in SPI\_CR2.

In this case, the receive buffer contents are not updated with the newly received data from the transmitter device. A read operation to the SPI\_DR register returns the previous correctly received data. All other subsequently transmitted half-words are lost.

Clearing the OVR bit is done by a read operation on the SPI\_DR register followed by a read access to the SPI\_SR register.

**Frame error flag (FRE)**

This flag can be set by hardware only if the I2S is configured in Slave mode. It is set if the external master is changing the WS line at a moment when the slave is not expected this change. If the synchronization is lost, to recover from this state and resynchronize the external master device with the I2S slave device, follow the steps below:

1. Disable the I2S
2. Re-enable it when the correct level is detected on the WS line (WS line is high in I2S mode, or low for MSB- or LSB-justified or PCM modes).

Desynchronization between the master and slave device may be due to noisy environment on the SCK communication clock or on the WS frame synchronization line. An error interrupt can be generated if the ERRIE bit is set. The desynchronization flag (FRE) is cleared by software when the status register is read.

**20.4.9 I<sup>2</sup>S interrupts**

[Table 92](#) provides the list of I<sup>2</sup>S interrupts.

**Table 92. I<sup>2</sup>S interrupt requests**

Interrupt event	Event flag	Enable Control bit
Transmit buffer empty flag	TXE	TXEIE
Receive buffer not empty flag	RXNE	RXNEIE
Overrun error	OVR	ERRIE
Underrun error	UDR	
Frame error flag	FRE	ERRIE

**20.4.10 DMA features**

DMA is working in exactly the same way as for the SPI mode. There is no difference on the I<sup>2</sup>S. Only the CRC feature is not available in I<sup>2</sup>S mode since there is no data transfer protection system.

## 20.5 SPI and I<sup>2</sup>S registers

Refer to [Section 1.1 on page 34](#) for a list of abbreviations used in register descriptions.

The peripheral registers have to be accessed by half-words (16 bits) or words (32 bits).

### 20.5.1 SPI control register 1 (SPI\_CR1)(not used in I<sup>2</sup>S mode)

Address offset: 0x00

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
BIDI MODE	BIDI OE	CRC EN	CRC NEXT	DFF	RX ONLY	SSM	SSI	LSB FIRST	SPE	BR [2:0]			MSTR	CPOL	CPHA
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

**Bit 15 BIDIMODE:** Bidirectional data mode enable  
 0: 2-line unidirectional data mode selected  
 1: 1-line bidirectional data mode selected  
*Note: This bit is not used in I<sup>2</sup>S mode*

**Bit 14 BIDIOE:** Output enable in bidirectional mode  
 This bit combined with the BIDImode bit selects the direction of transfer in bidirectional mode  
 0: Output disabled (receive-only mode)  
 1: Output enabled (transmit-only mode)  
*Note: This bit is not used in I<sup>2</sup>S mode.*  
*In master mode, the MOSI pin is used while the MISO pin is used in slave mode.*

**Bit 13 CRCEN:** Hardware CRC calculation enable  
 0: CRC calculation disabled  
 1: CRC calculation enabled  
*Note: This bit should be written only when SPI is disabled (SPE = '0') for correct operation.*  
*It is not used in I<sup>2</sup>S mode.*

**Bit 12 CRCNEXT:** CRC transfer next  
 0: Data phase (no CRC phase)  
 1: Next transfer is CRC (CRC phase)  
*Note: When the SPI is configured in full duplex or transmitter only modes, CRCNEXT must be written as soon as the last data is written to the SPI\_DR register.*  
*When the SPI is configured in receiver only mode, CRCNEXT must be set after the second last data reception.*  
*This bit should be kept cleared when the transfers are managed by DMA.*  
*It is not used in I<sup>2</sup>S mode.*

**Bit 11 DFF:** Data frame format  
 0: 8-bit data frame format is selected for transmission/reception  
 1: 16-bit data frame format is selected for transmission/reception  
*Note: This bit should be written only when SPI is disabled (SPE = '0') for correct operation.*  
*It is not used in I<sup>2</sup>S mode.*

**Bit 10 RXONLY:** Receive only

This bit combined with the BIDImode bit selects the direction of transfer in 2-line unidirectional mode. This bit is also useful in a multislave system in which this particular slave is not accessed, the output from the accessed slave is not corrupted.

0: Full duplex (Transmit and receive)

1: Output disabled (Receive-only mode)

*Note: This bit is not used in I<sup>2</sup>S mode*

**Bit 9 SSM:** Software slave management

When the SSM bit is set, the NSS pin input is replaced with the value from the SSI bit.

0: Software slave management disabled

1: Software slave management enabled

*Note: This bit is not used in I<sup>2</sup>S mode and SPI TI mode*

**Bit 8 SSI:** Internal slave select

This bit has an effect only when the SSM bit is set. The value of this bit is forced onto the NSS pin and the IO value of the NSS pin is ignored.

*Note: This bit is not used in I<sup>2</sup>S mode and SPI TI mode*

**Bit 7 LSBFIRST:** Frame format

0: MSB transmitted first

1: LSB transmitted first

*Note: This bit should not be changed when communication is ongoing.*

*It is not used in I<sup>2</sup>S mode and SPI TI mode*

**Bit 6 SPE:** SPI enable

0: Peripheral disabled

1: Peripheral enabled

*Note: This bit is not used in I<sup>2</sup>S mode.*

*When disabling the SPI, follow the procedure described in [Section 20.3.8: Disabling the SPI](#).*

**Bits 5:3 BR[2:0]:** Baud rate control

000:  $f_{PCLK}/2$

001:  $f_{PCLK}/4$

010:  $f_{PCLK}/8$

011:  $f_{PCLK}/16$

100:  $f_{PCLK}/32$

101:  $f_{PCLK}/64$

110:  $f_{PCLK}/128$

111:  $f_{PCLK}/256$

*Note: These bits should not be changed when communication is ongoing.*

*They are not used in I<sup>2</sup>S mode.*

- Bit 2 **MSTR**: Master selection
  - 0: Slave configuration
  - 1: Master configuration

*Note: This bit should not be changed when communication is ongoing.  
It is not used in I<sup>2</sup>S mode.*
- Bit1 **CPOL**: Clock polarity
  - 0: CK to 0 when idle
  - 1: CK to 1 when idle

*Note: This bit should not be changed when communication is ongoing.  
It is not used in I<sup>2</sup>S mode and SPI TI mode.*
- Bit 0 **CPHA**: Clock phase
  - 0: The first clock transition is the first data capture edge
  - 1: The second clock transition is the first data capture edge

*Note: This bit should not be changed when communication is ongoing.  
It is not used in I<sup>2</sup>S mode and SPI TI mode.*

### 20.5.2 SPI control register 2 (SPI\_CR2)

Address offset: 0x04

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved								TXEIE	RXNEIE	ERRIE	FRF	Res.	SSOE	TXDMAEN	RXDMAEN
								rw	rw	rw	rw		rw	rw	rw

Bits 15:8 Reserved, must be kept at reset value.

- Bit 7 **TXEIE**: Tx buffer empty interrupt enable
  - 0: TXE interrupt masked
  - 1: TXE interrupt not masked. Used to generate an interrupt request when the TXE flag is set.
- Bit 6 **RXNEIE**: RX buffer not empty interrupt enable
  - 0: RXNE interrupt masked
  - 1: RXNE interrupt not masked. Used to generate an interrupt request when the RXNE flag is set.
- Bit 5 **ERRIE**: Error interrupt enable
  - This bit controls the generation of an interrupt when an error condition occurs )(CRCERR, OVR, MODF in SPI mode, FRE in TI mode and UDR, OVR, and FRE in I<sup>2</sup>S mode).
  - 0: Error interrupt is masked
  - 1: Error interrupt is enabled
- Bit 4 **FRF**: Frame format
  - 0: SPI Motorola mode
  - 1 SPI TI mode

*Note: This bit is not used in I<sup>2</sup>S mode.*
- Bit 3 Reserved. Forced to 0 by hardware.

Bit 2 **SSOE**: SS output enable

- 0: SS output is disabled in master mode and the cell can work in multimaster configuration
- 1: SS output is enabled in master mode and when the cell is enabled. The cell cannot work in a multimaster environment.

*Note: This bit is not used in I<sup>2</sup>S mode and SPI TI mode.*

Bit 1 **TXDMAEN**: Tx buffer DMA enable

- When this bit is set, the DMA request is made whenever the TXE flag is set.
- 0: Tx buffer DMA disabled
- 1: Tx buffer DMA enabled

Bit 0 **RxDMAEN**: Rx buffer DMA enable

- When this bit is set, the DMA request is made whenever the RXNE flag is set.
- 0: Rx buffer DMA disabled
- 1: Rx buffer DMA enabled

### 20.5.3 SPI status register (SPI\_SR)

Address offset: 0x08

Reset value: 0x0002

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved							FRE	BSY	OVR	MODF	CRC ERR	UDR	CHSID E	TXE	RXNE
							r	r	r	r	rc_w0	r	r	r	r

Bits 15:9 Reserved. Forced to 0 by hardware.

Bit 8 **FRE**: Frame format error

- 0: No frame format error
- 1: A frame format error occurred
- This flag is set by hardware and cleared by software when the SPIx\_SR register is read.

*Note: This flag is used when the SPI operates in TI slave mode or I2S slave mode (refer to Section 20.3.10).*

Bit 7 **BSY**: Busy flag

- 0: SPI(or I2S) not busy
- 1: SPI(or I2S)is busy in communication or Tx buffer is not empty
- This flag is set and cleared by hardware.

*Note: BSY flag must be used with caution: refer to Section 20.3.7: Status flags and Section 20.3.8: Disabling the SPI.*

Bit 6 **OVR**: Overrun flag

- 0: No overrun occurred
- 1: Overrun occurred
- This flag is set by hardware and reset by a software sequence. Refer to Section 20.4.8 on page 595 for the software sequence.

Bit 5 **MODF**: Mode fault

- 0: No mode fault occurred
- 1: Mode fault occurred
- This flag is set by hardware and reset by a software sequence. Refer to Section 20.3.10 on page 577 for the software sequence.

*Note: This bit is not used in I<sup>2</sup>S mode*

- Bit 4 **CRCERR**: CRC error flag
  - 0: CRC value received matches the SPI\_RXCRCR value
  - 1: CRC value received does not match the SPI\_RXCRCR value

This flag is set by hardware and cleared by software writing 0.  
*Note: This bit is not used in P<sup>S</sup> mode.*
- Bit 3 **UDR**: Underrun flag
  - 0: No underrun occurred
  - 1: Underrun occurred

This flag is set by hardware and reset by a software sequence. Refer to [Section 20.4.8 on page 595](#) for the software sequence.  
*Note: This bit is not used in SPI mode.*
- Bit 2 **CHSIDE**: Channel side
  - 0: Channel Left has to be transmitted or has been received
  - 1: Channel Right has to be transmitted or has been received

*Note: This bit is not used for SPI mode and is meaningless in PCM mode.*
- Bit 1 **TXE**: Transmit buffer empty
  - 0: Tx buffer not empty
  - 1: Tx buffer empty
- Bit 0 **RXNE**: Receive buffer not empty
  - 0: Rx buffer empty
  - 1: Rx buffer not empty

### 20.5.4 SPI data register (SPI\_DR)

Address offset: 0x0C

Reset value: 0x0000

	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	DR[15:0]															
	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 15:0 **DR[15:0]**: Data register

Data received or to be transmitted.

The data register is split into 2 buffers - one for writing (Transmit Buffer) and another one for reading (Receive buffer). A write to the data register will write into the Tx buffer and a read from the data register will return the value held in the Rx buffer.

*Note: These notes apply to SPI mode:*

*Depending on the data frame format selection bit (DFF in SPI\_CR1 register), the data sent or received is either 8-bit or 16-bit. This selection has to be made before enabling the SPI to ensure correct operation.*

*For an 8-bit data frame, the buffers are 8-bit and only the LSB of the register (SPI\_DR[7:0]) is used for transmission/reception. When in reception mode, the MSB of the register (SPI\_DR[15:8]) is forced to 0.*

*For a 16-bit data frame, the buffers are 16-bit and the entire register, SPI\_DR[15:0] is used for transmission/reception.*

### 20.5.5 SPI CRC polynomial register (SPI\_CRCPR)(not used in I<sup>2</sup>S mode)

Address offset: 0x10

Reset value: 0x0007

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
CRCPOLY[15:0]															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 15:0 **CRCPOLY[15:0]**: CRC polynomial register

This register contains the polynomial for the CRC calculation.

The CRC polynomial (0007h) is the reset value of this register. Another polynomial can be configured as required.

*Note: These bits are not used for the I<sup>2</sup>S mode.*

### 20.5.6 SPI RX CRC register (SPI\_RXCR)(not used in I<sup>2</sup>S mode)

Address offset: 0x14

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
RXCRC[15:0]															
r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r

Bits 15:0 **RXCRC[15:0]**: Rx CRC register

When CRC calculation is enabled, the RxCRC[15:0] bits contain the computed CRC value of the subsequently received bytes. This register is reset when the CRCEN bit in SPI\_CR1 register is written to 1. The CRC is calculated serially using the polynomial programmed in the SPI\_CRCPR register.

Only the 8 LSB bits are considered when the data frame format is set to be 8-bit data (DFF bit of SPI\_CR1 is cleared). CRC calculation is done based on any CRC8 standard.

The entire 16-bits of this register are considered when a 16-bit data frame format is selected (DFF bit of the SPI\_CR1 register is set). CRC calculation is done based on any CRC16 standard.

*Note: A read to this register when the BSY Flag is set could return an incorrect value. These bits are not used for I<sup>2</sup>S mode*

### 20.5.7 SPI TX CRC register (SPI\_TXCR)(not used in I<sup>2</sup>S mode)

Address offset: 0x18

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
TXCRC[15:0]															
r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r

Bits 15:0 **TXCRC[15:0]**: Tx CRC register

When CRC calculation is enabled, the TxCRC[7:0] bits contain the computed CRC value of the subsequently transmitted bytes. This register is reset when the CRCEN bit of SPI\_CR1 is written to 1. The CRC is calculated serially using the polynomial programmed in the SPI\_CRCPR register.

Only the 8 LSB bits are considered when the data frame format is set to be 8-bit data (DFF bit of SPI\_CR1 is cleared). CRC calculation is done based on any CRC8 standard.

The entire 16-bits of this register are considered when a 16-bit data frame format is selected (DFF bit of the SPI\_CR1 register is set). CRC calculation is done based on any CRC16 standard.

*Note: A read to this register when the BSY flag is set could return an incorrect value. These bits are not used for I<sup>2</sup>S mode.*

### 20.5.8 SPI\_I<sup>2</sup>S configuration register (SPI\_I2SCFGR)

Address offset: 0x1C

Reset value: 0x0000

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved				I2SMOD	I2SE	I2SCFG		PCMSY NC	Res.	I2SSTD		CKPOL	DATLEN		CHLEN
				rw	rw	rw	rw	rw		rw	rw	rw	rw	rw	rw

Bits 15:12 Reserved, must be kept at reset value.

Bit 11 **I2SMOD**: I2S mode selection

0: SPI mode is selected

1: I2S mode is selected

*Note: This bit should be configured when the SPI or I<sup>2</sup>S is disabled*

Bit 10 **I2SE**: I2S Enable

0: I<sup>2</sup>S peripheral is disabled

1: I<sup>2</sup>S peripheral is enabled

*Note: This bit is not used in SPI mode.*

Bits 9:8 **I2SCFG**: I2S configuration mode

00: Slave - transmit

01: Slave - receive

10: Master - transmit

11: Master - receive

*Note: This bit should be configured when the I<sup>2</sup>S is disabled.*

*It is not used in SPI mode.*

Bit 7 **PCMSYNC**: PCM frame synchronization

0: Short frame synchronization

1: Long frame synchronization

*Note: This bit has a meaning only if I2SSTD = 11 (PCM standard is used)*

*It is not used in SPI mode.*

Bit 6 Reserved: forced at 0 by hardware



Bits 5:4 **I2SSTD**: I2S standard selection

- 00: I<sup>2</sup>S Philips standard.
- 01: MSB justified standard (left justified)
- 10: LSB justified standard (right justified)
- 11: PCM standard

For more details on I<sup>2</sup>S standards, refer to [Section 20.4.3 on page 581](#). *Not used in SPI mode.*

*Note: For correct operation, these bits should be configured when the I<sup>2</sup>S is disabled.*

Bit 3 **CKPOL**: Steady state clock polarity

- 0: I<sup>2</sup>S clock steady state is low level
- 1: I<sup>2</sup>S clock steady state is high level

*Note: For correct operation, this bit should be configured when the I<sup>2</sup>S is disabled.*

*This bit is not used in SPI mode*

Bits 2:1 **DATLEN**: Data length to be transferred

- 00: 16-bit data length
- 01: 24-bit data length
- 10: 32-bit data length
- 11: Not allowed

*Note: For correct operation, these bits should be configured when the I<sup>2</sup>S is disabled.*

*This bit is not used in SPI mode.*

Bit 0 **CHLEN**: Channel length (number of bits per audio channel)

- 0: 16-bit wide
- 1: 32-bit wide

The bit write operation has a meaning only if DATLEN = 00 otherwise the channel length is fixed to 32-bit by hardware whatever the value filled in. *Not used in SPI mode.*

*Note: For correct operation, this bit should be configured when the I<sup>2</sup>S is disabled.*

### 20.5.9 SPI\_I<sup>2</sup>S prescaler register (SPI\_I2SPR)

Address offset: 0x20

Reset value: 0000 0010 (0x0002)

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved						MCKOE	ODD	I2SDIV							
						rw	rw	rw							

Bits 15:10 Reserved, must be kept at reset value.

Bit 9 **MCKOE**: Master clock output enable

0: Master clock output is disabled

1: Master clock output is enabled

*Note: This bit should be configured when the  $\dot{P}S$  is disabled. It is used only when the  $\dot{P}S$  is in master mode.*

*This bit is not used in SPI mode.*

Bit 8 **ODD**: Odd factor for the prescaler

0: real divider value is = I2SDIV \*2

1: real divider value is = (I2SDIV \* 2)+1

Refer to [Section 20.4.4 on page 589](#). Not used in SPI mode.

*Note: This bit should be configured when the  $\dot{P}S$  is disabled. It is used only when the  $\dot{P}S$  is in master mode.*

Bits 7:0 **I2SDIV**: I2S Linear prescaler

I2SDIV [7:0] = 0 or I2SDIV [7:0] = 1 are forbidden values.

Refer to [Section 20.4.4 on page 589](#). Not used in SPI mode.

*Note: These bits should be configured when the  $\dot{P}S$  is disabled. It is used only when the  $\dot{P}S$  is in master mode.*

### 20.5.10 SPI register map

The table provides shows the SPI register map and reset values.

**Table 93. SPI register map and reset values**

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0																				
0x00	<b>SPI_CR1</b>	Reserved																BIDIMODE	BIDIOE	CRCEN	CRCNEXT	DFE	RXONLY	SSM	SSI	LSBFIRST	SPE	BR [2:0]																									
	Reset value																	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0								
0x08	<b>SPI_SR</b>	Reserved																							FRE	BSY	OVR	MODF	CRCERR	UDR	CHSIDE	TXE	RXNE																				
	Reset value																								0	0	0	0	0	0	0	0	1	0																			
0x0C	<b>SPI_DR</b>	Reserved																DR[15:0]																																			
	Reset value																	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0										
0x10	<b>SPI_CRCPR</b>	Reserved																CRCPOLY[15:0]																																			
	Reset value																	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1									
0x14	<b>SPI_RXCRCR</b>	Reserved																RxCRC[15:0]																																			
	Reset value																	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0								
0x18	<b>SPI_TXCRCR</b>	Reserved																TxCRC[15:0]																																			
	Reset value																	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0								
0x1C	<b>SPI_I2SCFGR</b>	Reserved																I2SMOD	I2SE	I2SCFG	PCMSYNC	Reserved		I2SSTD	CKPOL	DATLEN	CHLEN																										
	Reset value																	0	0	0	0			0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0									
0x20	<b>SPI_I2SPR</b>	Reserved																							MCKOE	ODD	I2SDIV																										
	Reset value																								0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Refer to [Table 1 on page 38](#) for the register boundary addresses.



## 21 Secure digital input/output interface (SDIO)

### 21.1 SDIO main features

The SD/SDIO MMC card host interface (SDIO) provides an interface between the APB2 peripheral bus and MultiMediaCards (MMCs), SD memory cards, SDIO cards and CE-ATA devices.

The MultiMediaCard system specifications are available through the MultiMediaCard Association website at <http://www.jedec.org/>, published by the MMCA technical committee.

SD memory card and SD I/O card system specifications are available through the SD card Association website at <http://www.sdcard.org>.

CE-ATA system specifications are available through the CE-ATA workgroup website.

The SDIO features include the following:

- Full compliance with *MultiMediaCard System Specification Version 4.2*. Card support for three different databus modes: 1-bit (default), 4-bit and 8-bit
- Full compatibility with previous versions of MultiMediaCards (forward compatibility)
- Full compliance with *SD Memory Card Specifications Version 2.0*
- Full compliance with *SD I/O Card Specification Version 2.0*: card support for two different databus modes: 1-bit (default) and 4-bit
- Full support of the CE-ATA features (full compliance with *CE-ATA digital protocol Rev1.1*)
- Data transfer up to 48 MHz for the 8 bit mode
- Data and command output enable signals to control external bidirectional drivers.

*Note:* The SDIO does not have an SPI-compatible communication mode.

*The SD memory card protocol is a superset of the MultiMediaCard protocol as defined in the MultiMediaCard system specification V2.11. Several commands required for SD memory devices are not supported by either SD I/O-only cards or the I/O portion of combo cards. Some of these commands have no use in SD I/O devices, such as erase commands, and thus are not supported in the SDIO. In addition, several commands are different between SD memory cards and SD I/O cards and thus are not supported in the SDIO. For details refer to SD I/O card Specification Version 1.0. CE-ATA is supported over the MMC electrical interface using a protocol that utilizes the existing MMC access primitives. The interface electrical and signaling definition is as defined in the MMC reference.*

The MultiMediaCard/SD bus connects cards to the controller.

The current version of the SDIO supports only one SD/SDIO/MMC4.2 card at any one time and a stack of MMC4.1 or previous.

### 21.2 SDIO bus topology

Communication over the bus is based on command and data transfers.

The basic transaction on the MultiMediaCard/SD/SD I/O bus is the command/response transaction. These types of bus transaction transfer their information directly within the command or response structure. In addition, some operations have a data token.

Data transfers to/from SD/SDIO memory cards are done in data blocks. Data transfers to/from MMC are done data blocks or streams. Data transfers to/from the CE-ATA Devices are done in data blocks.

Figure 229. SDIO “no response” and “no data” operations

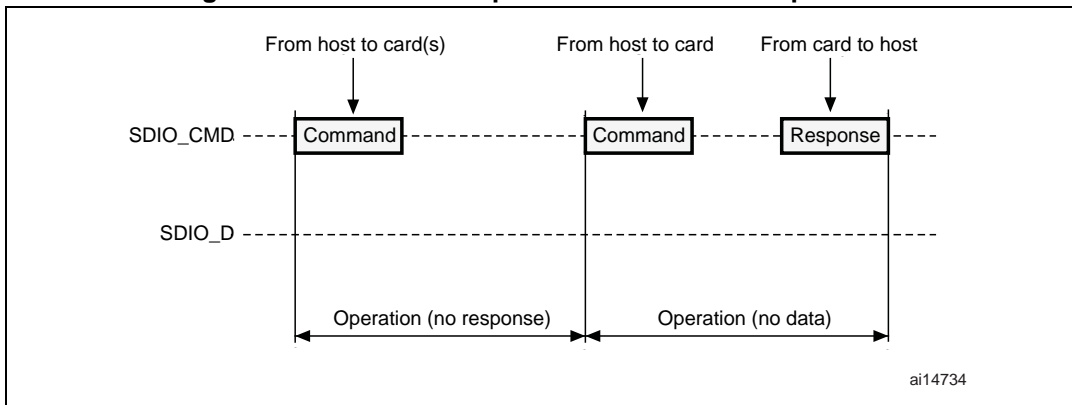


Figure 230. SDIO (multiple) block read operation

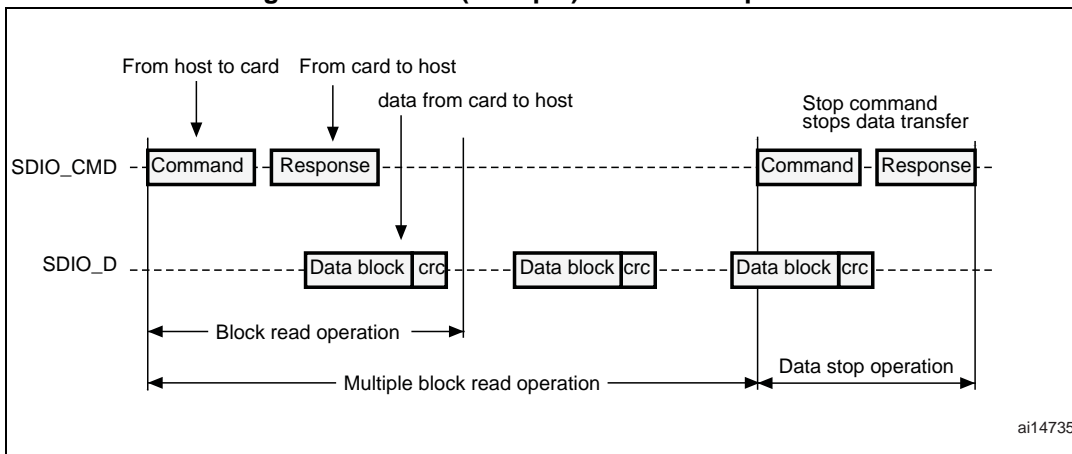
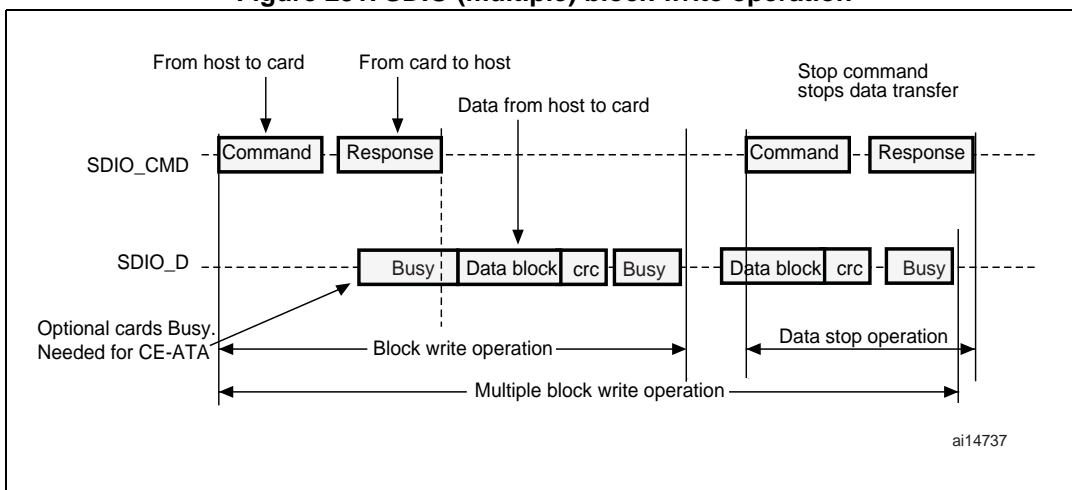


Figure 231. SDIO (multiple) block write operation



Note: The SDIO will not send any data as long as the Busy signal is asserted (SDIO\_D0 pulled low).

Figure 232. SDIO sequential read operation

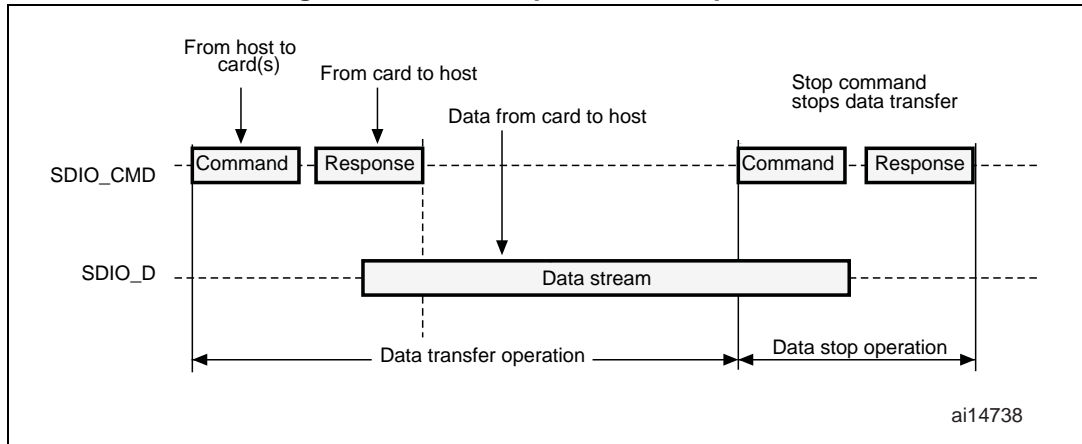
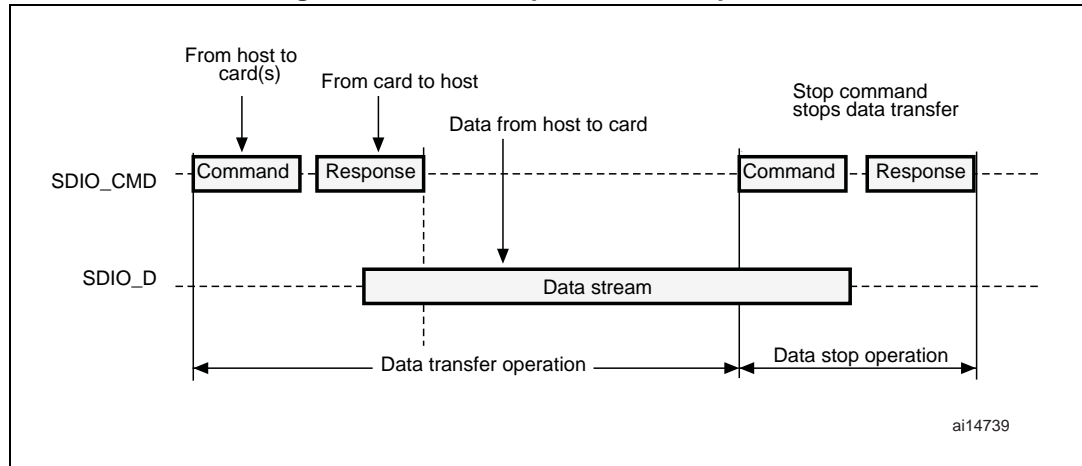


Figure 233. SDIO sequential write operation

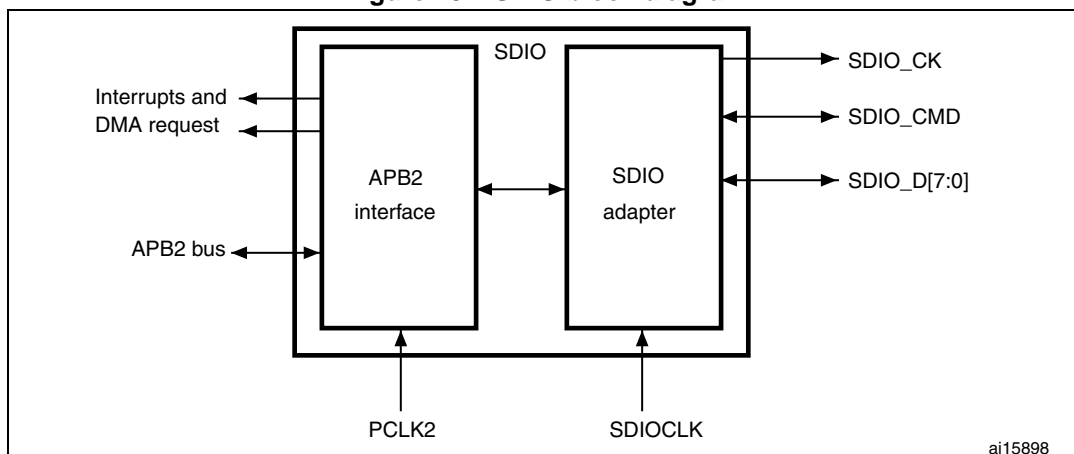


### 21.3 SDIO functional description

The SDIO consists of two parts:

- The SDIO adapter block provides all functions specific to the MMC/SD/SD I/O card such as the clock generation unit, command and data transfer.
- The APB2 interface accesses the SDIO adapter registers, and generates interrupt and DMA request signals.

Figure 234. SDIO block diagram



By default SDIO\_D0 is used for data transfer. After initialization, the host can change the databus width.

If a MultiMediaCard is connected to the bus, SDIO\_D0, SDIO\_D[3:0] or SDIO\_D[7:0] can be used for data transfer. MMC V3.31 or previous, supports only 1 bit of data so only SDIO\_D0 can be used.

If an SD or SD I/O card is connected to the bus, data transfer can be configured by the host to use SDIO\_D0 or SDIO\_D[3:0]. All data lines are operating in push-pull mode.

**SDIO\_CMD** has two operational modes:

- Open-drain for initialization (only for MMCV3.31 or previous)
- Push-pull for command transfer (SD/SD I/O card MMC4.2 use push-pull drivers also for initialization)

**SDIO\_CK** is the clock to the card: one bit is transferred on both command and data lines with each clock cycle. The clock frequency can vary between 0 MHz and 20 MHz (for a MultiMediaCard V3.31), between 0 and 48 MHz for a MultiMediaCard V4.0/4.2, or between 0 and 25 MHz (for an SD/SD I/O card).

The SDIO uses two clock signals:

- SDIO adapter clock (SDIOCLK = 48 MHz)
- APB2 bus clock (PCLK2)

PCLK2 and SDIO\_CK clock frequencies must respect the following condition:

$$\text{Frequency(PCLK2)} \geq 3/8 \times \text{Frequency(SDIO\_CK)}$$

The signals shown in [Table 94](#) are used on the MultiMediaCard/SD/SD I/O card bus.

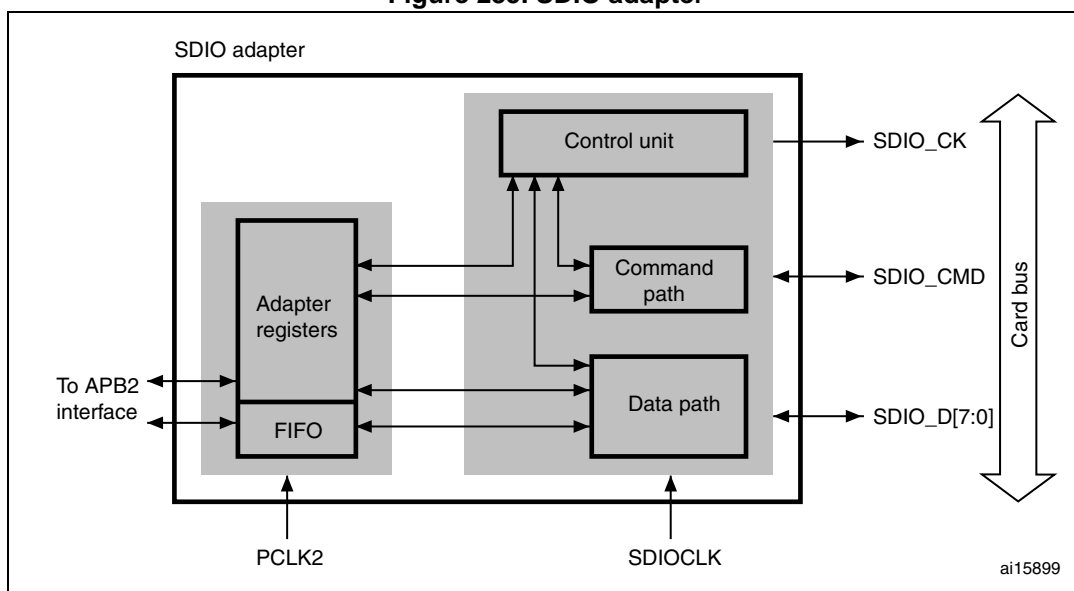
Table 94. SDIO I/O definitions

Pin	Direction	Description
SDIO_CK	Output	MultiMediaCard/SD/SDIO card clock. This pin is the clock from host to card.
SDIO_CMD	Bidirectional	MultiMediaCard/SD/SDIO card command. This pin is the bidirectional command/response signal.
SDIO_D[7:0]	Bidirectional	MultiMediaCard/SD/SDIO card data. These pins are the bidirectional databus.

### 21.3.1 SDIO adapter

Figure 235 shows a simplified block diagram of an SDIO adapter.

Figure 235. SDIO adapter



The SDIO adapter is a multimedia/secure digital memory card bus master that provides an interface to a multimedia card stack or to a secure digital memory card. It consists of five subunits:

- Adapter register block
- Control unit
- Command path
- Data path
- Data FIFO

*Note:* The adapter registers and FIFO use the APB2 bus clock domain (PCLK2). The control unit, command path and data path use the SDIO adapter clock domain (SDIOCLK).

#### Adapter register block

The adapter register block contains all system registers. This block also generates the signals that clear the static flags in the multimedia card. The clear signals are generated when 1 is written into the corresponding bit location in the SDIO Clear register.



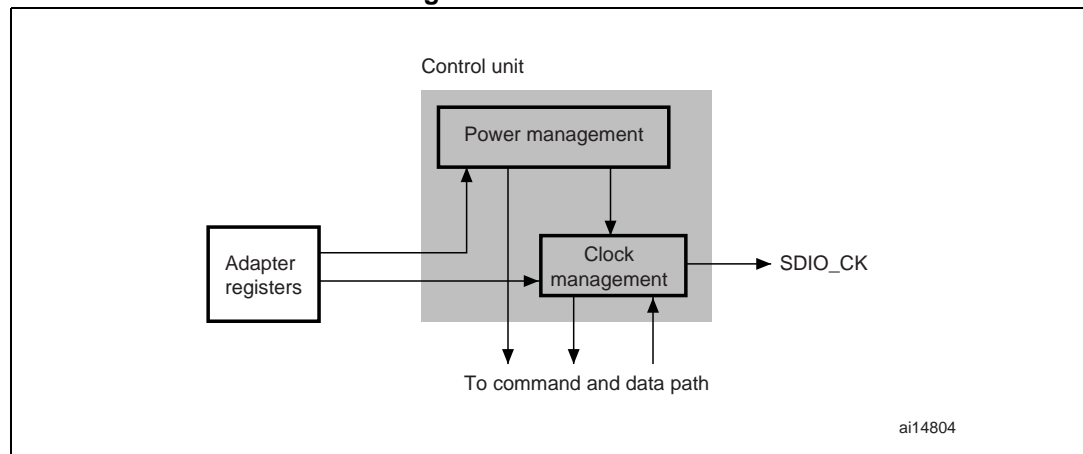
### Control unit

The control unit contains the power management functions and the clock divider for the memory card clock.

There are three power phases:

- power-off
- power-up
- power-on

**Figure 236. Control unit**



The control unit is illustrated in [Figure 236](#). It consists of a power management subunit and a clock management subunit.

The power management subunit disables the card bus output signals during the power-off and power-up phases.

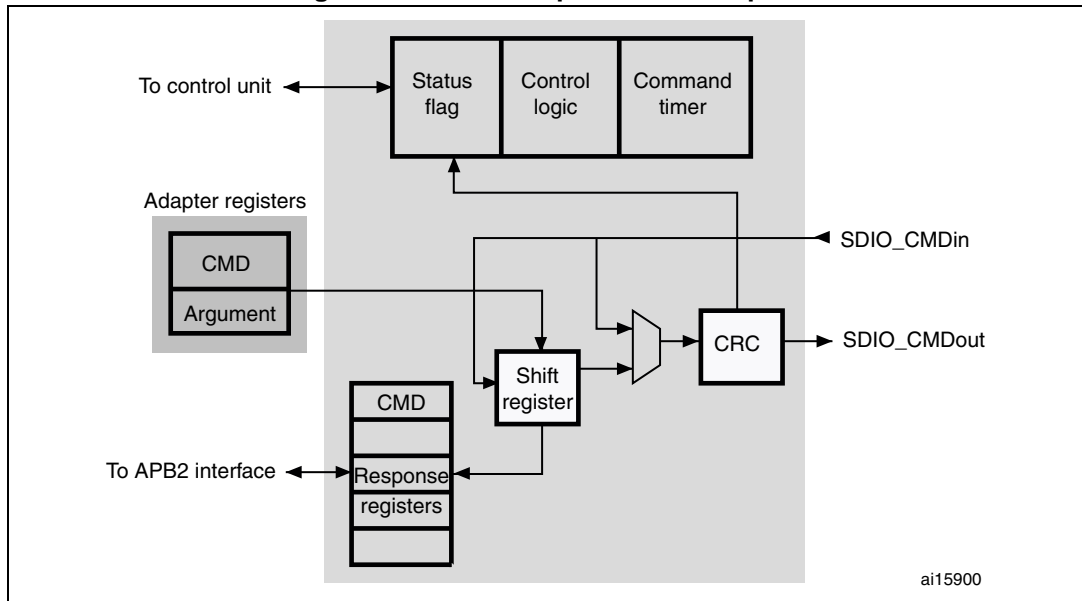
The clock management subunit generates and controls the SDIO\_CK signal. The SDIO\_CK output can use either the clock divide or the clock bypass mode. The clock output is inactive:

- after reset
- during the power-off or power-up phases
- if the power saving mode is enabled and the card bus is in the Idle state (eight clock periods after both the command and data path subunits enter the Idle phase)

### Command path

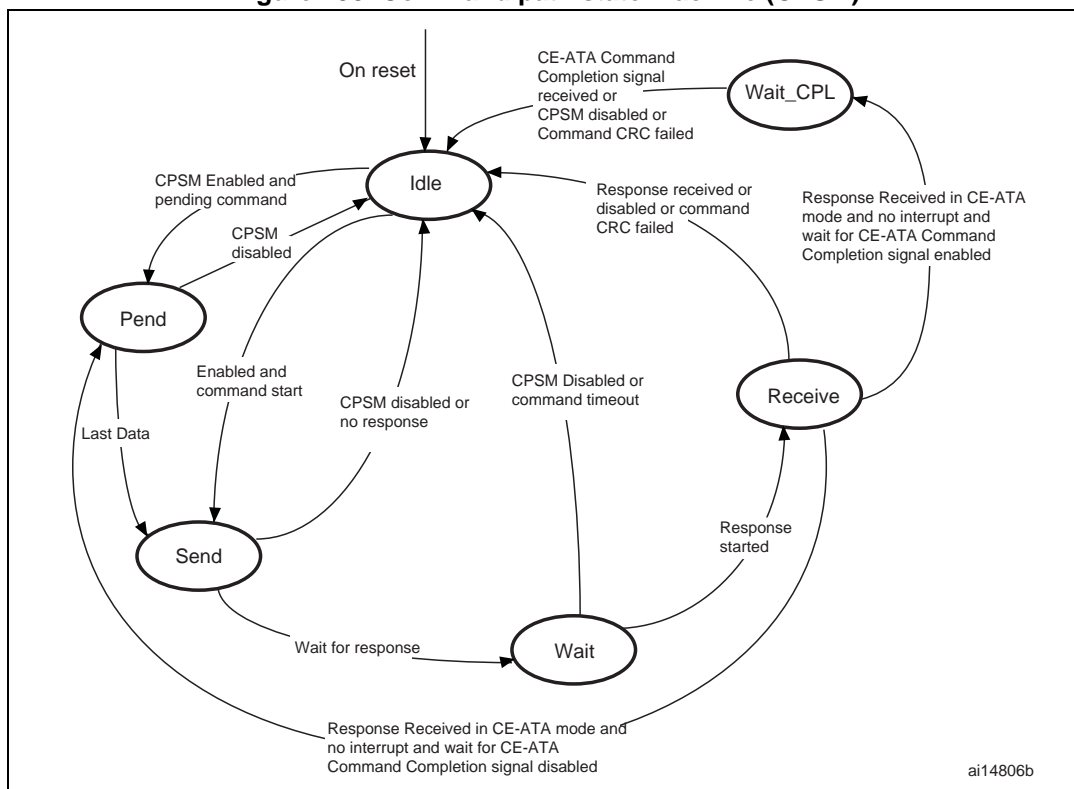
The command path unit sends commands to and receives responses from the cards.

Figure 237. SDIO adapter command path



- Command path state machine (CPSM)
  - When the command register is written to and the enable bit is set, command transfer starts. When the command has been sent, the command path state machine (CPSM) sets the status flags and enters the Idle state if a response is not required. If a response is required, it waits for the response (see [Figure 238 on page 614](#)). When the response is received, the received CRC code and the internally generated code are compared, and the appropriate status flags are set.

Figure 238. Command path state machine (CPSM)



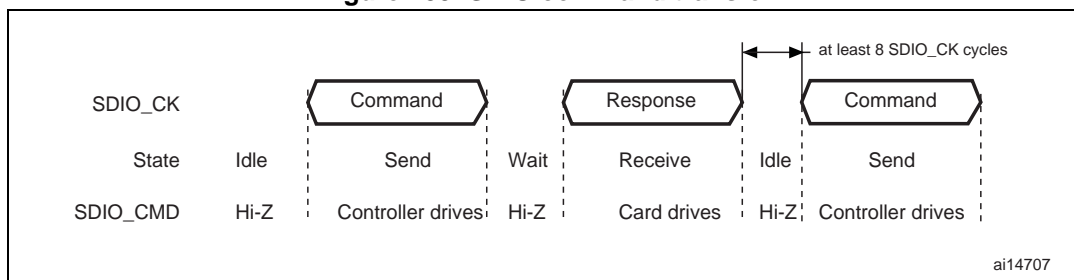
When the Wait state is entered, the command timer starts running. If the timeout is reached before the CPSM moves to the Receive state, the timeout flag is set and the Idle state is entered.

*Note:* The command timeout has a fixed value of 64 SDIO\_CK clock periods.

If the interrupt bit is set in the command register, the timer is disabled and the CPSM waits for an interrupt request from one of the cards. If a pending bit is set in the command register, the CPSM enters the Pend state, and waits for a CmdPend signal from the data path subunit. When CmdPend is detected, the CPSM moves to the Send state. This enables the data counter to trigger the stop command transmission.

*Note:* The CPSM remains in the Idle state for at least eight SDIO\_CK periods to meet the  $N_{CC}$  and  $N_{RC}$  timing constraints.  $N_{CC}$  is the minimum delay between two host commands, and  $N_{RC}$  is the minimum delay between the host command and the card response.

Figure 239. SDIO command transfer



- Command format
    - Command: a command is a token that starts an operation. Command are sent from the host either to a single card (addressed command) or to all connected cards (broadcast command are available for MMC V3.31 or previous). Commands are transferred serially on the CMD line. All commands have a fixed length of 48 bits. The general format for a command token for MultiMediaCards, SD-Memory cards and SDIO-Cards is shown in [Table 95](#). CE-ATA commands are an extension of MMC commands V4.2, and so have the same format.
- The command path operates in a half-duplex mode, so that commands and responses can either be sent or received. If the CPSM is not in the Send state, the SDIO\_CMD output is in the Hi-Z state, as shown in [Figure 239 on page 615](#). Data on SDIO\_CMD are synchronous with the rising edge of SDIO\_CK. [Table](#) shows the command format.

Table 95. Command format

Bit position	Width	Value	Description
47	1	0	Start bit
46	1	1	Transmission bit
[45:40]	6	-	Command index
[39:8]	32	-	Argument
[7:1]	7	-	CRC7
0	1	1	End bit

- Response: a response is a token that is sent from an addressed card (or synchronously from all connected cards for MMC V3.31 or previous), to the host as an answer to a previously received command. Responses are transferred serially on the CMD line.

The SDIO supports two response types. Both use CRC error checking:

- 48 bit short response
- 136 bit long response

*Note: If the response does not contain a CRC (CMD1 response), the device driver must ignore the CRC failed status.*

Table 96. Short response format

Bit position	Width	Value	Description
47	1	0	Start bit
46	1	0	Transmission bit
[45:40]	6	-	Command index
[39:8]	32	-	Argument
[7:1]	7	-	CRC7(or 1111111)
0	1	1	End bit

Table 97. Long response format

Bit position	Width	Value	Description
135	1	0	Start bit
134	1	0	Transmission bit
[133:128]	6	111111	Reserved
[127:1]	127	-	CID or CSD (including internal CRC7)
0	1	1	End bit

The command register contains the command index (six bits sent to a card) and the command type. These determine whether the command requires a response, and whether the response is 48 or 136 bits long (see [Section 21.9.4 on page 651](#)). The command path implements the status flags shown in [Table 98](#):

Table 98. Command path status flags

Flag	Description
CMDREND	Set if response CRC is OK.
CCRCFAIL	Set if response CRC fails.
CMDSENT	Set when command (that does not require response) is sent
CTIMEOUT	Response timeout.
CMDACT	Command transfer in progress.

The CRC generator calculates the CRC checksum for all bits before the CRC code. This includes the start bit, transmitter bit, command index, and command argument (or card status). The CRC checksum is calculated for the first 120 bits of CID or CSD for the long response format. Note that the start bit, transmitter bit and the six reserved bits are not used in the CRC calculation.

The CRC checksum is a 7-bit value:

$$\text{CRC}[6:0] = \text{Remainder} [(M(x) * x^7) / G(x)]$$

$$G(x) = x^7 + x^3 + 1$$

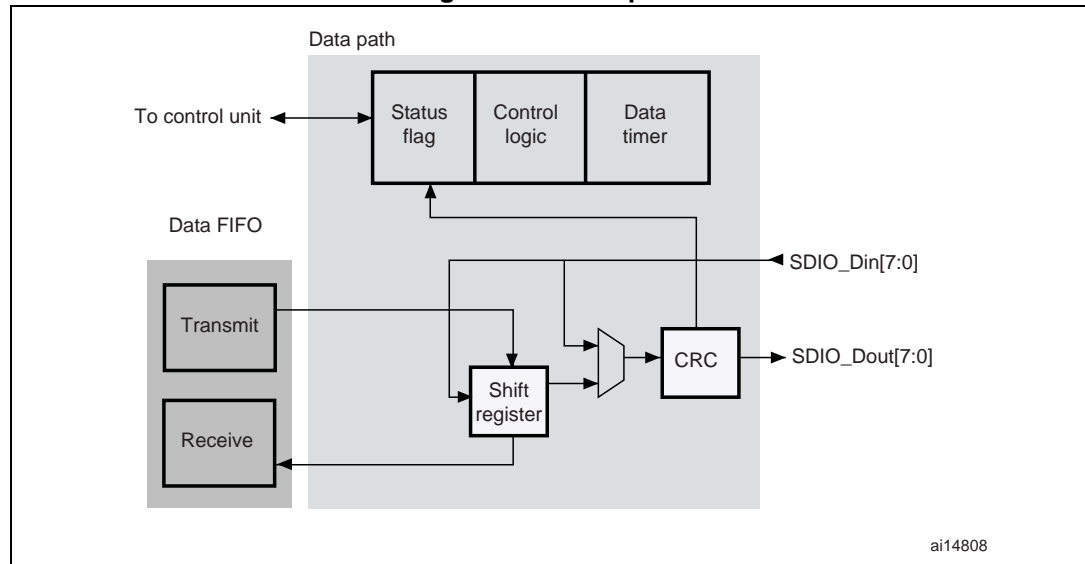
$$M(x) = (\text{start bit}) * x^{39} + \dots + (\text{last bit before CRC}) * x^0, \text{ or}$$

$$M(x) = (\text{start bit}) * x^{119} + \dots + (\text{last bit before CRC}) * x^0$$

## Data path

The data path subunit transfers data to and from cards. [Figure 240](#) shows a block diagram of the data path.

**Figure 240. Data path**



The card databus width can be programmed using the clock control register. If the 4-bit wide bus mode is enabled, data is transferred at four bits per clock cycle over all four data signals (SDIO\_D[3:0]). If the 8-bit wide bus mode is enabled, data is transferred at eight bits per clock cycle over all eight data signals (SDIO\_D[7:0]). If the wide bus mode is not enabled, only one bit per clock cycle is transferred over SDIO\_D0.

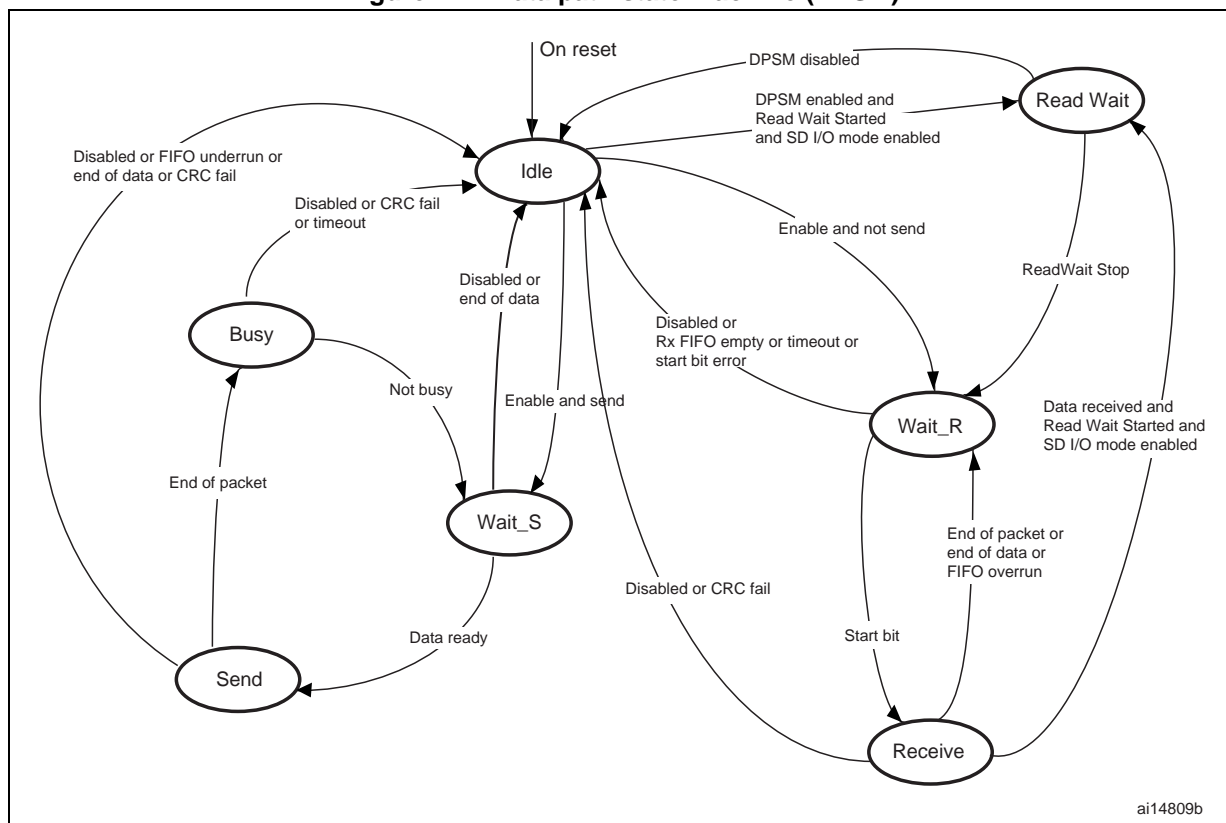
Depending on the transfer direction (send or receive), the data path state machine (DPSM) moves to the Wait\_S or Wait\_R state when it is enabled:

- Send: the DPSM moves to the Wait\_S state. If there is data in the transmit FIFO, the DPSM moves to the Send state, and the data path subunit starts sending data to a card.
- Receive: the DPSM moves to the Wait\_R state and waits for a start bit. When it receives a start bit, the DPSM moves to the Receive state, and the data path subunit starts receiving data from a card.

### Data path state machine (DPSM)

The DPSM operates at SDIO\_CK frequency. Data on the card bus signals is synchronous to the rising edge of SDIO\_CK. The DPSM has six states, as shown in [Figure 241: Data path state machine \(DPSM\)](#).

Figure 241. Data path state machine (DPSM)



- Idle: the data path is inactive, and the SDIO\_D[7:0] outputs are in Hi-Z. When the data control register is written and the enable bit is set, the DPSM loads the data counter with a new value and, depending on the data direction bit, moves to either the Wait\_S or the Wait\_R state.
- Wait\_R: if the data counter equals zero, the DPSM moves to the Idle state when the receive FIFO is empty. If the data counter is not zero, the DPSM waits for a start bit on SDIO\_D. The DPSM moves to the Receive state if it receives a start bit before a timeout, and loads the data block counter. If it reaches a timeout before it detects a start bit, or a start bit error occurs, it moves to the Idle state and sets the timeout status flag.
- Receive: serial data received from a card is packed in bytes and written to the data FIFO. Depending on the transfer mode bit in the data control register, the data transfer mode can be either block or stream:
  - In block mode, when the data block counter reaches zero, the DPSM waits until it receives the CRC code. If the received code matches the internally generated CRC code, the DPSM moves to the Wait\_R state. If not, the CRC fail status flag is set and the DPSM moves to the Idle state.
  - In stream mode, the DPSM receives data while the data counter is not zero. When the counter is zero, the remaining data in the shift register is written to the data FIFO, and the DPSM moves to the Wait\_R state.

If a FIFO overrun error occurs, the DPSM sets the FIFO error flag and moves to the Idle state:
- Wait\_S: the DPSM moves to the Idle state if the data counter is zero. If not, it waits until the data FIFO empty flag is deasserted, and moves to the Send state.

*Note:* The DPSM remains in the Wait\_S state for at least two clock periods to meet the  $N_{WR}$  timing requirements, where  $N_{WR}$  is the number of clock cycles between the reception of the card response and the start of the data transfer from the host.

- Send: the DPSM starts sending data to a card. Depending on the transfer mode bit in the data control register, the data transfer mode can be either block or stream:
  - In block mode, when the data block counter reaches zero, the DPSM sends an internally generated CRC code and end bit, and moves to the Busy state.
  - In stream mode, the DPSM sends data to a card while the enable bit is high and the data counter is not zero. It then moves to the Idle state.

If a FIFO underrun error occurs, the DPSM sets the FIFO error flag and moves to the Idle state.

- Busy: the DPSM waits for the CRC status flag:
  - If it does not receive a positive CRC status, it moves to the Idle state and sets the CRC fail status flag.
  - If it receives a positive CRC status, it moves to the Wait\_S state if SDIO\_D0 is not low (the card is not busy).

If a timeout occurs while the DPSM is in the Busy state, it sets the data timeout flag and moves to the Idle state.

The data timer is enabled when the DPSM is in the Wait\_R or Busy state, and generates the data timeout error:

- When transmitting data, the timeout occurs if the DPSM stays in the Busy state for longer than the programmed timeout period
- When receiving data, the timeout occurs if the end of the data is not true, and if the DPSM stays in the Wait\_R state for longer than the programmed timeout period.
- **Data:** data can be transferred from the card to the host or vice versa. Data is transferred via the data lines. They are stored in a FIFO of 32 words, each word is 32 bits wide.

**Table 99. Data token format**

Description	Start bit	Data	CRC16	End bit
Block Data	0	-	yes	1
Stream Data	0	-	no	1



## Data FIFO

The data FIFO (first-in-first-out) subunit is a data buffer with a transmit and receive unit.

The FIFO contains a 32-bit wide, 32-word deep data buffer, and transmit and receive logic. Because the data FIFO operates in the APB2 clock domain (PCLK2), all signals from the subunits in the SDIO clock domain (SDIOCLK) are resynchronized.

Depending on the TXACT and RXACT flags, the FIFO can be disabled, transmit enabled, or receive enabled. TXACT and RXACT are driven by the data path subunit and are mutually exclusive:

- The transmit FIFO refers to the transmit logic and data buffer when TXACT is asserted
- The receive FIFO refers to the receive logic and data buffer when RXACT is asserted
- Transmit FIFO:
 

Data can be written to the transmit FIFO through the APB2 interface when the SDIO is enabled for transmission.

The transmit FIFO is accessible via 32 sequential addresses. The transmit FIFO contains a data output register that holds the data word pointed to by the read pointer. When the data path subunit has loaded its shift register, it increments the read pointer and drives new data out.

If the transmit FIFO is disabled, all status flags are deasserted. The data path subunit asserts TXACT when it transmits data.

**Table 100. Transmit FIFO status flags**

Flag	Description
TXFIFO	Set to high when all 32 transmit FIFO words contain valid data.
TXFIFOE	Set to high when the transmit FIFO does not contain valid data.
TXFIFOHE	Set to high when 8 or more transmit FIFO words are empty. This flag can be used as a DMA request.
TXDAVL	Set to high when the transmit FIFO contains valid data. This flag is the inverse of the TXFIFOE flag.
TXUNDERR	Set to high when an underrun error occurs. This flag is cleared by writing to the SDIO Clear register.

- Receive FIFO
 

When the data path subunit receives a word of data, it drives the data on the write databus. The write pointer is incremented after the write operation completes. On the read side, the contents of the FIFO word pointed to by the current value of the read pointer is driven onto the read databus. If the receive FIFO is disabled, all status flags are deasserted, and the read and write pointers are reset. The data path subunit asserts RXACT when it receives data. [Table 101](#) lists the receive FIFO status flags. The receive FIFO is accessible via 32 sequential addresses.

Table 101. Receive FIFO status flags

Flag	Description
RXFIFO	Set to high when all 32 receive FIFO words contain valid data
RXFIFOE	Set to high when the receive FIFO does not contain valid data.
RXFIFOHF	Set to high when 8 or more receive FIFO words contain valid data. This flag can be used as a DMA request.
RXDAVL	Set to high when the receive FIFO is not empty. This flag is the inverse of the RXFIFOE flag.
RXOVERR	Set to high when an overrun error occurs. This flag is cleared by writing to the SDIO Clear register.

### 21.3.2 SDIO APB2 interface

The APB2 interface generates the interrupt and DMA requests, and accesses the SDIO adapter registers and the data FIFO. It consists of a data path, register decoder, and interrupt/DMA logic.

#### SDIO interrupts

The interrupt logic generates an interrupt request signal that is asserted when at least one of the selected status flags is high. A mask register is provided to allow selection of the conditions that will generate an interrupt. A status flag generates the interrupt request if a corresponding mask flag is set.

#### SDIO/DMA interface - procedure for data transfers between the SDIO and memory

In the example shown, the transfer is from the SDIO host controller to an MMC (512 bytes using CMD24 (WRITE\_BLOCK)). The SDIO FIFO is filled by data stored in a memory using the DMA controller.

1. Do the card identification process
2. Increase the SDIO\_CK frequency
3. Select the card by sending CMD7
4. Configure the DMA2 as follows:
  - a) Enable DMA2 controller and clear any pending interrupts.
  - b) Program the DMA2\_Stream3 or DMA2\_Stream6 Channel4 source address register with the memory location's base address and DMA2\_Stream3 or

- DMA2\_Stream6 Channel4 destination address register with the SDIO\_FIFO register address.
- c) Program DMA2\_Stream3 or DMA2\_Stream6 Channel4 control register (memory increment, not peripheral increment, peripheral and source width is word size).
  - d) Program DMA2\_Stream3 or DMA2\_Stream6 Channel4 to select the peripheral as flow controller (set PFCTRL bit in DMA\_S3CR or DMA\_S6CR configuration register).
  - e) Configure the incremental burst transfer to 4 beats (at least from peripheral side) in DMA2\_Stream3 or DMA2\_Stream6 Channel4.
  - f) Enable DMA2\_Stream3 or DMA2\_Stream6 Channel4
5. Send CMD24 (WRITE\_BLOCK) as follows:
- a) Program the SDIO data length register (SDIO data timer register should be already programmed before the card identification process).
  - b) Program the SDIO argument register with the address location of the card where data is to be transferred.
  - c) Program the SDIO command register: CmdIndex with 24 (WRITE\_BLOCK); WaitResp with '1' (SDIO card host waits for a response); CPSMEN with '1' (SDIO card host enabled to send a command). Other fields are at their reset value.
  - d) Wait for SDIO\_STA[6] = CMDREND interrupt, then program the SDIO data control register: DTEN with '1' (SDIO card host enabled to send data); DTDIR with '0' (from controller to card); DTMODE with '0' (block data transfer); DMAEN with '1' (DMA enabled); DBLOCKSIZE with 0x9 (512 bytes). Other fields are don't care.
  - e) Wait for SDIO\_STA[10] = DBCKEND.
6. Check that no channels are still enabled by polling the DMA Enabled Channel Status register.

## 21.4 Card functional description

### 21.4.1 Card identification mode

While in card identification mode the host resets all cards, validates the operation voltage range, identifies cards and sets a relative card address (RCA) for each card on the bus. All data communications in the card identification mode use the command line (CMD) only.

### 21.4.2 Card reset

The GO\_IDLE\_STATE command (CMD0) is the software reset command and it puts the MultiMediaCard and SD memory in the Idle state. The IO\_RW\_DIRECT command (CMD52) resets the SD I/O card. After power-up or CMD0, all cards output bus drivers are in the high-impedance state and the cards are initialized with a default relative card address (RCA=0x0001) and with a default driver stage register setting (lowest speed, highest driving current capability).

### 21.4.3 Operating voltage range validation

All cards can communicate with the SDIO card host using any operating voltage within the specification range. The supported minimum and maximum  $V_{DD}$  values are defined in the operation conditions register (OCR) on the card.

Cards that store the card identification number (CID) and card specific data (CSD) in the payload memory are able to communicate this information only under data-transfer  $V_{DD}$  conditions. When the SDIO card host module and the card have incompatible  $V_{DD}$  ranges, the card is not able to complete the identification cycle and cannot send CSD data. For this purpose, the special commands, `SEND_OP_COND` (CMD1), `SD_APP_OP_COND` (ACMD41 for SD Memory), and `IO_SEND_OP_COND` (CMD5 for SD I/O), are designed to provide a mechanism to identify and reject cards that do not match the  $V_{DD}$  range desired by the SDIO card host. The SDIO card host sends the required  $V_{DD}$  voltage window as the operand of these commands. Cards that cannot perform data transfer in the specified range disconnect from the bus and go to the inactive state.

By using these commands without including the voltage range as the operand, the SDIO card host can query each card and determine the common voltage range before placing out-of-range cards in the inactive state. This query is used when the SDIO card host is able to select a common voltage range or when the user requires notification that cards are not usable.

#### 21.4.4 Card identification process

The card identification process differs for MultiMediaCards and SD cards. For MultiMediaCard cards, the identification process starts at clock rate  $F_{od}$ . The SDIO\_CMD line output drivers are open-drain and allow parallel card operation during this process. The registration process is accomplished as follows:

1. The bus is activated.
2. The SDIO card host broadcasts `SEND_OP_COND` (CMD1) to receive operation conditions.
3. The response is the wired AND operation of the operation condition registers from all cards.
4. Incompatible cards are placed in the inactive state.
5. The SDIO card host broadcasts `ALL_SEND_CID` (CMD2) to all active cards.
6. The active cards simultaneously send their CID numbers serially. Cards with outgoing CID bits that do not match the bits on the command line stop transmitting and must wait for the next identification cycle. One card successfully transmits a full CID to the SDIO card host and enters the Identification state.
7. The SDIO card host issues `SET_RELATIVE_ADDR` (CMD3) to that card. This new address is called the relative card address (RCA); it is shorter than the CID and addresses the card. The assigned card changes to the Standby state, it does not react to further identification cycles, and its output switches from open-drain to push-pull.
8. The SDIO card host repeats steps 5 through 7 until it receives a timeout condition.

For the SD card, the identification process starts at clock rate  $F_{od}$ , and the SDIO\_CMD line output drives are push-pull drivers instead of open-drain. The registration process is accomplished as follows:

1. The bus is activated.
2. The SDIO card host broadcasts `SD_APP_OP_COND` (ACMD41).
3. The cards respond with the contents of their operation condition registers.
4. The incompatible cards are placed in the inactive state.
5. The SDIO card host broadcasts `ALL_SEND_CID` (CMD2) to all active cards.
6. The cards send back their unique card identification numbers (CIDs) and enter the Identification state.
7. The SDIO card host issues `SET_RELATIVE_ADDR` (CMD3) to an active card with an address. This new address is called the relative card address (RCA); it is shorter than the CID and addresses the card. The assigned card changes to the Standby state. The SDIO card host can reissue this command to change the RCA. The RCA of the card is the last assigned value.
8. The SDIO card host repeats steps 5 through 7 with all active cards.

For the SD I/O card, the registration process is accomplished as follows:

1. The bus is activated.
2. The SDIO card host sends `IO_SEND_OP_COND` (CMD5).
3. The cards respond with the contents of their operation condition registers.
4. The incompatible cards are set to the inactive state.
5. The SDIO card host issues `SET_RELATIVE_ADDR` (CMD3) to an active card with an address. This new address is called the relative card address (RCA); it is shorter than the CID and addresses the card. The assigned card changes to the Standby state. The SDIO card host can reissue this command to change the RCA. The RCA of the card is the last assigned value.

### 21.4.5 Block write

During block write (CMD24 - 27) one or more blocks of data are transferred from the host to the card with a CRC appended to the end of each block by the host. A card supporting block write is always able to accept a block of data defined by `WRITE_BL_LEN`. If the CRC fails, the card indicates the failure on the `SDIO_D` line and the transferred data are discarded and not written, and all further transmitted blocks (in multiple block write mode) are ignored.

If the host uses partial blocks whose accumulated length is not block aligned and, block misalignment is not allowed (CSD parameter `WRITE_BLK_MISALIGN` is not set), the card will detect the block misalignment error before the beginning of the first misaligned block. (`ADDRESS_ERROR` error bit is set in the status register). The write operation will also be aborted if the host tries to write over a write-protected area. In this case, however, the card will set the `WP_VIOLATION` bit.

Programming of the CID and CSD registers does not require a previous block length setting. The transferred data is also CRC protected. If a part of the CSD or CID register is stored in ROM, then this unchangeable part must match the corresponding part of the receive buffer. If this match fails, then the card reports an error and does not change any register contents. Some cards may require long and unpredictable times to write a block of data. After receiving a block of data and completing the CRC check, the card begins writing and holds the `SDIO_D` line low if its write buffer is full and unable to accept new data from a new `WRITE_BLOCK` command. The host may poll the status of the card with a `SEND_STATUS` command (CMD13) at any time, and the card will respond with its status. The `READY_FOR_DATA` status bit indicates whether the card can accept new data or whether the write process is still in progress. The host may deselect the card by issuing CMD7 (to

select a different card), which will place the card in the Disconnect state and release the SDIO\_D line(s) without interrupting the write operation. When selecting the card again, it will reactivate busy indication by pulling SDIO\_D to low if programming is still in progress and the write buffer is unavailable.

#### 21.4.6 Block read

In Block read mode the basic unit of data transfer is a block whose maximum size is defined in the CSD (READ\_BL\_LEN). If READ\_BL\_PARTIAL is set, smaller blocks whose start and end addresses are entirely contained within one physical block (as defined by READ\_BL\_LEN) may also be transmitted. A CRC is appended to the end of each block, ensuring data transfer integrity. CMD17 (READ\_SINGLE\_BLOCK) initiates a block read and after completing the transfer, the card returns to the Transfer state.

CMD18 (READ\_MULTIPLE\_BLOCK) starts a transfer of several consecutive blocks.

The host can abort reading at any time, within a multiple block operation, regardless of its type. Transaction abort is done by sending the stop transmission command.

If the card detects an error (for example, out of range, address misalignment or internal error) during a multiple block read operation (both types) it stops the data transmission and remains in the data state. The host must then abort the operation by sending the stop transmission command. The read error is reported in the response to the stop transmission command.

If the host sends a stop transmission command after the card transmits the last block of a multiple block operation with a predefined number of blocks, it is responded to as an illegal command, since the card is no longer in the data state. If the host uses partial blocks whose accumulated length is not block-aligned and block misalignment is not allowed, the card detects a block misalignment error condition at the beginning of the first misaligned block (ADDRESS\_ERROR error bit is set in the status register).

#### 21.4.7 Stream access, stream write and stream read (MultiMediaCard only)

In stream mode, data is transferred in bytes and no CRC is appended at the end of each block.

##### Stream write (MultiMediaCard only)

WRITE\_DAT\_UNTIL\_STOP (CMD20) starts the data transfer from the SDIO card host to the card, beginning at the specified address and continuing until the SDIO card host issues a stop command. When partial blocks are allowed (CSD parameter WRITE\_BL\_PARTIAL is set), the data stream can start and stop at any address within the card address space, otherwise it can only start and stop at block boundaries. Because the amount of data to be transferred is not determined in advance, a CRC cannot be used. When the end of the memory range is reached while sending data and no stop command is sent by the SD card host, any additional transferred data are discarded.

The maximum clock frequency for a stream write operation is given by the following equation fields of the card-specific data register:

$$\text{Maximumspeed} = \text{MIN}(\text{TRANSPEED}, \frac{(8 \times 2^{\text{writeblen}})(-\text{NSAC})}{\text{TAAC} \times \text{R2WFACTOR}})$$

- Maximumspeed = maximum write frequency
- TRANSPEED = maximum data transfer rate
- writeblen = maximum write data block length
- NSAC = data read access time 2 in CLK cycles
- TAAC = data read access time 1
- R2WFACTOR = write speed factor

If the host attempts to use a higher frequency, the card may not be able to process the data and stop programming, set the **OVERRUN** error bit in the status register, and while ignoring all further data transfer, wait (in the receive data state) for a stop command. The write operation is also aborted if the host tries to write over a write-protected area. In this case, however, the card sets the **WP\_VIOLATION** bit.

### Stream read (MultiMediaCard only)

**READ\_DAT\_UNTIL\_STOP** (CMD11) controls a stream-oriented data transfer.

This command instructs the card to send its data, starting at a specified address, until the SDIO card host sends **STOP\_TRANSMISSION** (CMD12). The stop command has an execution delay due to the serial command transmission and the data transfer stops after the end bit of the stop command. When the end of the memory range is reached while sending data and no stop command is sent by the SDIO card host, any subsequent data sent are considered undefined.

The maximum clock frequency for a stream read operation is given by the following equation and uses fields of the card specific data register.

$$\text{Maximumspeed} = \text{MIN}(\text{TRANSPEED}, \frac{(8 \times 2^{\text{readblen}})(-\text{NSAC})}{\text{TAAC} \times \text{R2WFACTOR}})$$

- Maximumspeed = maximum read frequency
- TRANSPEED = maximum data transfer rate
- readblen = maximum read data block length
- writeblen = maximum write data block length
- NSAC = data read access time 2 in CLK cycles
- TAAC = data read access time 1
- R2WFACTOR = write speed factor

If the host attempts to use a higher frequency, the card is not able to sustain data transfer. If this happens, the card sets the **UNDERRUN** error bit in the status register, aborts the transmission and waits in the data state for a stop command.

### 21.4.8 Erase: group erase and sector erase

The erasable unit of the MultiMediaCard is the erase group. The erase group is measured in write blocks, which are the basic writable units of the card. The size of the erase group is a card-specific parameter and defined in the CSD.

The host can erase a contiguous range of Erase Groups. Starting the erase process is a three-step sequence.

First the host defines the start address of the range using the `ERASE_GROUP_START` (CMD35) command, next it defines the last address of the range using the `ERASE_GROUP_END` (CMD36) command and, finally, it starts the erase process by issuing the `ERASE` (CMD38) command. The address field in the erase commands is an Erase Group address in byte units. The card ignores all LSBs below the Erase Group size, effectively rounding the address down to the Erase Group boundary.

If an erase command is received out of sequence, the card sets the `ERASE_SEQ_ERROR` bit in the status register and resets the whole sequence.

If an out-of-sequence (neither of the erase commands, except `SEND_STATUS`) command received, the card sets the `ERASE_RESET` status bit in the status register, resets the erase sequence and executes the last command.

If the erase range includes write protected blocks, they are left intact and only unprotected blocks are erased. The `WP_ERASE_SKIP` status bit in the status register is set.

The card indicates that an erase is in progress by holding `SDIO_D` low. The actual erase time may be quite long, and the host may issue `CMD7` to deselect the card.

### 21.4.9 Wide bus selection or deselection

Wide bus (4-bit bus width) operation mode is selected or deselected using `SET_BUS_WIDTH` (ACMD6). The default bus width after power-up or `GO_IDLE_STATE` (CMD0) is 1 bit. `SET_BUS_WIDTH` (ACMD6) is only valid in a transfer state, which means that the bus width can be changed only after a card is selected by `SELECT/DESELECT_CARD` (CMD7).

### 21.4.10 Protection management

Three write protection methods for the cards are supported in the SDIO card host module:

1. internal card write protection (card responsibility)
2. mechanical write protection switch (SDIO card host module responsibility only)
3. password-protected card lock operation

#### Internal card write protection

Card data can be protected against write and erase. By setting the permanent or temporary write-protect bits in the CSD, the entire card can be permanently write-protected by the manufacturer or content provider. For cards that support write protection of groups of sectors by setting the `WP_GRP_ENABLE` bit in the CSD, portions of the data can be protected, and the write protection can be changed by the application. The write protection is in units of `WP_GRP_SIZE` sectors as specified in the CSD. The `SET_WRITE_PROT` and `CLR_WRITE_PROT` commands control the protection of the addressed group. The `SEND_WRITE_PROT` command is similar to a single block read command. The card sends a data block containing 32 write protection bits (representing 32 write protect groups starting



at the specified address) followed by 16 CRC bits. The address field in the write protect commands is a group address in byte units.

The card ignores all LSBs below the group size.

### Mechanical write protect switch

A mechanical sliding tab on the side of the card allows the user to set or clear the write protection on a card. When the sliding tab is positioned with the window open, the card is write-protected, and when the window is closed, the card contents can be changed. A matched switch on the socket side indicates to the SDIO card host module that the card is write-protected. The SDIO card host module is responsible for protecting the card. The position of the write protect switch is unknown to the internal circuitry of the card.

### Password protect

The password protection feature enables the SDIO card host module to lock and unlock a card with a password. The password is stored in the 128-bit PWD register and its size is set in the 8-bit PWD\_LEN register. These registers are nonvolatile so that a power cycle does not erase them. Locked cards respond to and execute certain commands. This means that the SDIO card host module is allowed to reset, initialize, select, and query for status, however it is not allowed to access data on the card. When the password is set (as indicated by a nonzero value of PWD\_LEN), the card is locked automatically after power-up. As with the CSD and CID register write commands, the lock/unlock commands are available in the transfer state only. In this state, the command does not include an address argument and the card must be selected before using it. The card lock/unlock commands have the structure and bus transaction types of a regular single-block write command. The transferred data block includes all of the required information for the command (the password setting mode, the PWD itself, and card lock/unlock). The command data block size is defined by the SDIO card host module before it sends the card lock/unlock command, and has the structure shown in [Table 115](#).

The bit settings are as follows:

- ERASE: setting it forces an erase operation. All other bits must be zero, and only the command byte is sent
- LOCK\_UNLOCK: setting it locks the card. LOCK\_UNLOCK can be set simultaneously with SET\_PWD, however not with CLR\_PWD
- CLR\_PWD: setting it clears the password data
- SET\_PWD: setting it saves the password data to memory
- PWD\_LEN: it defines the length of the password in bytes
- PWD: the password (new or currently used, depending on the command)

The following sections list the command sequences to set/reset a password, lock/unlock the card, and force an erase.

### Setting the password

1. Select a card (SELECT/DESELECT\_CARD, CMD7), if none is already selected.
2. Define the block length (SET\_BLOCKLEN, CMD16) to send, given by the 8-bit card lock/unlock mode, the 8-bit PWD\_LEN, and the number of bytes of the new password.

When a password replacement is done, the block size must take into account that both the old and the new passwords are sent with the command.

3. Send LOCK/UNLOCK (CMD42) with the appropriate data block size on the data line including the 16-bit CRC. The data block indicates the mode (SET\_PWD = 1), the length (PWD\_LEN), and the password (PWD) itself. When a password replacement is done, the length value (PWD\_LEN) includes the length of both passwords, the old and the new one, and the PWD field includes the old password (currently used) followed by the new password.
4. When the password is matched, the new password and its size are saved into the PWD and PWD\_LEN fields, respectively. When the old password sent does not correspond (in size and/or content) to the expected password, the LOCK\_UNLOCK\_FAILED error bit is set in the card status register, and the password is not changed.

The password length field (PWD\_LEN) indicates whether a password is currently set. When this field is nonzero, there is a password set and the card locks itself after power-up. It is possible to lock the card immediately in the current power session by setting the LOCK\_UNLOCK bit (while setting the password) or sending an additional command for card locking.

### Resetting the password

1. Select a card (SELECT/DESELECT\_CARD, CMD7), if none is already selected.
2. Define the block length (SET\_BLOCKLEN, CMD16) to send, given by the 8-bit card lock/unlock mode, the 8-bit PWD\_LEN, and the number of bytes in the currently used password.
3. Send LOCK/UNLOCK (CMD42) with the appropriate data block size on the data line including the 16-bit CRC. The data block indicates the mode (CLR\_PWD = 1), the length (PWD\_LEN) and the password (PWD) itself. The LOCK\_UNLOCK bit is ignored.
4. When the password is matched, the PWD field is cleared and PWD\_LEN is set to 0. When the password sent does not correspond (in size and/or content) to the expected password, the LOCK\_UNLOCK\_FAILED error bit is set in the card status register, and the password is not changed.

### Locking a card

1. Select a card (SELECT/DESELECT\_CARD, CMD7), if none is already selected.
2. Define the block length (SET\_BLOCKLEN, CMD16) to send, given by the 8-bit card lock/unlock mode (byte 0 in [Table 115](#)), the 8-bit PWD\_LEN, and the number of bytes of the current password.
3. Send LOCK/UNLOCK (CMD42) with the appropriate data block size on the data line including the 16-bit CRC. The data block indicates the mode (LOCK\_UNLOCK = 1), the length (PWD\_LEN), and the password (PWD) itself.
4. When the password is matched, the card is locked and the CARD\_IS\_LOCKED status bit is set in the card status register. When the password sent does not correspond (in size and/or content) to the expected password, the LOCK\_UNLOCK\_FAILED error bit is set in the card status register, and the lock fails.

It is possible to set the password and to lock the card in the same sequence. In this case, the SDIO card host module performs all the required steps for setting the password (see [Setting the password on page 628](#)), however it is necessary to set the LOCK\_UNLOCK bit in Step 3 when the new password command is sent.

When the password is previously set (PWD\_LEN is not 0), the card is locked automatically after power-on reset. An attempt to lock a locked card or to lock a card that does not have a password fails and the LOCK\_UNLOCK\_FAILED error bit is set in the card status register.

### Unlocking the card

1. Select a card (SELECT/DESELECT\_CARD, CMD7), if none is already selected.
2. Define the block length (SET\_BLOCKLEN, CMD16) to send, given by the 8-bit cardlock/unlock mode (byte 0 in [Table 115](#)), the 8-bit PWD\_LEN, and the number of bytes of the current password.
3. Send LOCK/UNLOCK (CMD42) with the appropriate data block size on the data line including the 16-bit CRC. The data block indicates the mode (LOCK\_UNLOCK = 0), the length (PWD\_LEN), and the password (PWD) itself.
4. When the password is matched, the card is unlocked and the CARD\_IS\_LOCKED status bit is cleared in the card status register. When the password sent is not correct in size and/or content and does not correspond to the expected password, the LOCK\_UNLOCK\_FAILED error bit is set in the card status register, and the card remains locked.

The unlocking function is only valid for the current power session. When the PWD field is not clear, the card is locked automatically on the next power-up.

An attempt to unlock an unlocked card fails and the LOCK\_UNLOCK\_FAILED error bit is set in the card status register.

### Forcing erase

If the user has forgotten the password (PWD content), it is possible to access the card after clearing all the data on the card. This forced erase operation erases all card data and all password data.

1. Select a card (SELECT/DESELECT\_CARD, CMD7), if none is already selected.
2. Set the block length (SET\_BLOCKLEN, CMD16) to 1 byte. Only the 8-bit card lock/unlock byte (byte 0 in [Table 115](#)) is sent.
3. Send LOCK/UNLOCK (CMD42) with the appropriate data byte on the data line including the 16-bit CRC. The data block indicates the mode (ERASE = 1). All other bits must be zero.
4. When the ERASE bit is the only bit set in the data field, all card contents are erased, including the PWD and PWD\_LEN fields, and the card is no longer locked. When any other bits are set, the LOCK\_UNLOCK\_FAILED error bit is set in the card status register and the card retains all of its data, and remains locked.

An attempt to use a force erase on an unlocked card fails and the LOCK\_UNLOCK\_FAILED error bit is set in the card status register.

## 21.4.11 Card status register

The response format R1 contains a 32-bit field named card status. This field is intended to transmit the card status information (which may be stored in a local status register) to the host. If not specified otherwise, the status entries are always related to the previously issued command.

[Table 102](#) defines the different entries of the status. The type and clear condition fields in the table are abbreviated as follows:

Type:

- E: error bit
- S: status bit
- R: detected and set for the actual command response
- X: detected and set during command execution. The SDIO card host must poll the card by issuing the status command to read these bits.

Clear condition:

- A: according to the card current state
- B: always related to the previous command. Reception of a valid command clears it (with a delay of one command)
- C: clear by read

**Table 102. Card status**

Bits	Identifier	Type	Value	Description	Clear condition
31	ADDRESS_OUT_OF_RANGE	E R X	'0'= no error '1'= error	The command address argument was out of the allowed range for this card. A multiple block or stream read/write operation is (although started in a valid address) attempting to read or write beyond the card capacity.	C
30	ADDRESS_MISALIGN	-	'0'= no error '1'= error	The commands address argument (in accordance with the currently set block length) positions the first data block misaligned to the card physical blocks. A multiple block read/write operation (although started with a valid address/block-length combination) is attempting to read or write a data block which is not aligned with the physical blocks of the card.	C
29	BLOCK_LEN_ERROR	-	'0'= no error '1'= error	Either the argument of a SET_BLOCKLEN command exceeds the maximum value allowed for the card, or the previously defined block length is illegal for the current command (e.g. the host issues a write command, the current block length is smaller than the maximum allowed value for the card and it is not allowed to write partial blocks)	C
28	ERASE_SEQ_ERROR	-	'0'= no error '1'= error	An error in the sequence of erase commands occurred.	C
27	ERASE_PARAM	E X	'0'= no error '1'= error	An invalid selection of erase groups for erase occurred.	C
26	WP_VIOLATION	E X	'0'= no error '1'= error	Attempt to program a write-protected block.	C

Table 102. Card status (continued)

Bits	Identifier	Type	Value	Description	Clear condition
25	CARD_IS_LOCKED	S R	'0' = card unlocked '1' = card locked	When set, signals that the card is locked by the host	A
24	LOCK_UNLOCK_FAILED	E X	'0' = no error '1' = error	Set when a sequence or password error has been detected in lock/unlock card command	C
23	COM_CRC_ERROR	E R	'0' = no error '1' = error	The CRC check of the previous command failed.	B
22	ILLEGAL_COMMAND	E R	'0' = no error '1' = error	Command not legal for the card state	B
21	CARD_ECC_FAILED	E X	'0' = success '1' = failure	Card internal ECC was applied but failed to correct the data.	C
20	CC_ERROR	E R	'0' = no error '1' = error	(Undefined by the standard) A card error occurred, which is not related to the host command.	C
19	ERROR	E X	'0' = no error '1' = error	(Undefined by the standard) A generic card error related to the (and detected during) execution of the last host command (e.g. read or write failures).	C
18	Reserved				
17	Reserved				
16	CID/CSD_OVERWRITE	E X	'0' = no error '1' = error	Can be either of the following errors: – The CID register has already been written and cannot be overwritten – The read-only section of the CSD does not match the card contents – An attempt to reverse the copy (set as original) or permanent WP (unprotected) bits was made	C
15	WP_ERASE_SKIP	E X	'0' = not protected '1' = protected	<b>Set when only partial address space was erased due to existing write</b>	C
14	CARD_ECC_DISABLED	S X	'0' = enabled '1' = disabled	The command has been executed without using the internal ECC.	A
13	ERASE_RESET	-	'0' = cleared '1' = set	An erase sequence was cleared before executing because an out of erase sequence command was received (commands other than CMD35, CMD36, CMD38 or CMD13)	C

Table 102. Card status (continued)

Bits	Identifier	Type	Value	Description	Clear condition
12:9	CURRENT_STATE	S R	0 = Idle 1 = Ready 2 = Ident 3 = Stby 4 = Tran 5 = Data 6 = Rcv 7 = Prg 8 = Dis 9 = Btst 10-15 = reserved	The state of the card when receiving the command. If the command execution causes a state change, it will be visible to the host in the response on the next command. The four bits are interpreted as a binary number between 0 and 15.	B
8	READY_FOR_DATA	S R	'0' = not ready '1' = ready	Corresponds to buffer empty signalling on the bus	-
7	SWITCH_ERROR	E X	'0' = no error '1' = switch error	If set, the card did not switch to the expected mode as requested by the SWITCH command	B
6	Reserved				
5	APP_CMD	S R	'0' = Disabled '1' = Enabled	The card will expect ACMD, or an indication that the command has been interpreted as ACMD	C
4	Reserved for SD I/O Card				
3	AKE_SEQ_ERROR	E R	'0' = no error '1' = error	Error in the sequence of the authentication process	C
2	Reserved for application specific commands				
1	Reserved for manufacturer test mode				
0					

### 21.4.12 SD status register

The SD status contains status bits that are related to the SD memory card proprietary features and may be used for future application-specific usage. The size of the SD Status is one data block of 512 bits. The contents of this register are transmitted to the SDIO card host if ACMD13 is sent (CMD55 followed with CMD13). ACMD13 can be sent to a card in transfer state only (card is selected).

Table 103 defines the different entries of the SD status register. The type and clear condition fields in the table are abbreviated as follows:

Type:

- E: error bit
- S: status bit
- R: detected and set for the actual command response
- X: detected and set during command execution. The SDIO card Host must poll the card by issuing the status command to read these bits

Clear condition:

- A: according to the card current state
- B: always related to the previous command. Reception of a valid command clears it (with a delay of one command)
- C: clear by read

**Table 103. SD status**

Bits	Identifier	Type	Value	Description	Clear condition
511: 510	DAT_BUS_WIDTH	S R	'00'= 1 (default) '01'= reserved '10'= 4 bit width '11'= reserved	Shows the currently defined databus width that was defined by SET_BUS_WIDTH command	A
509	SECURED_MODE	S R	'0'= Not in the mode '1'= In Secured Mode	Card is in Secured Mode of operation (refer to the "SD Security Specification").	A
508: 496	Reserved				
495: 480	SD_CARD_TYPE	S R	'00xxh'= SD Memory Cards as defined in Physical Spec Ver1.01-2.00 ('x'= don't care). The following cards are currently defined: '0000'= Regular SD RD/WR Card. '0001'= SD ROM Card	In the future, the 8 LSBs will be used to define different variations of an SD memory card (each bit will define different SD types). The 8 MSBs will be used to define SD Cards that do not comply with current SD physical layer specification.	A
479: 448	SIZE_OF_PROTECTED_AREA	S R	Size of protected area (See below)	(See below)	A
447: 440	SPEED_CLASS	S R	Speed Class of the card (See below)	(See below)	A
439: 432	PERFORMANCE_MOVE	S R	Performance of move indicated by 1 [MB/s] step. (See below)	(See below)	A
431:428	AU_SIZE	S R	Size of AU (See below)	(See below)	A
427:424	Reserved				
423:408	ERASE_SIZE	S R	Number of AUs to be erased at a time	(See below)	A
407:402	ERASE_TIMEOUT	S R	Timeout value for erasing areas specified by UNIT_OF_ERASE_AU	(See below)	A
401:400	ERASE_OFFSET	S R	Fixed offset value added to erase time.	(See below)	A
399:312	Reserved				
311:0	Reserved for Manufacturer				

**SIZE\_OF\_PROTECTED\_AREA**

Setting this field differs between standard- and high-capacity cards. In the case of a standard-capacity card, the capacity of protected area is calculated as follows:

$$\text{Protected area} = \text{SIZE\_OF\_PROTECTED\_AREA\_} * \text{MULT} * \text{BLOCK\_LEN.}$$

SIZE\_OF\_PROTECTED\_AREA is specified by the unit in MULT\*BLOCK\_LEN.

In the case of a high-capacity card, the capacity of protected area is specified in this field:

$$\text{Protected area} = \text{SIZE\_OF\_PROTECTED\_AREA}$$

SIZE\_OF\_PROTECTED\_AREA is specified by the unit in bytes.

**SPEED\_CLASS**

This 8-bit field indicates the speed class and the value can be calculated by  $P_W/2$  (where  $P_W$  is the write performance).

**Table 104. Speed class code field**

SPEED_CLASS	Value definition
00h	Class 0
01h	Class 2
02h	Class 4
03h	Class 6
04h – FFh	Reserved

**PERFORMANCE\_MOVE**

This 8-bit field indicates Pm (performance move) and the value can be set by 1 [MB/sec] steps. If the card does not move used RUs (recording units), Pm should be considered as infinity. Setting the field to FFh means infinity.

**Table 105. Performance move field**

PERFORMANCE_MOVE	Value definition
00h	Not defined
01h	1 [MB/sec]
02h	02h 2 [MB/sec]
-----	-----
FEh	254 [MB/sec]
FFh	Infinity



**AU\_SIZE**

This 4-bit field indicates the AU size and the value can be selected in the power of 2 base from 16 KB.

**Table 106. AU\_SIZE field**

AU_SIZE	Value definition
00h	Not defined
01h	16 KB
02h	32 KB
03h	64 KB
04h	128 KB
05h	256 KB
06h	512 KB
07h	1 MB
08h	2 MB
09h	4 MB
Ah – Fh	Reserved

The maximum AU size, which depends on the card capacity, is defined in [Table 107](#). The card can be set to any AU size between RU size and maximum AU size.

**Table 107. Maximum AU size**

Capacity	16 MB-64 MB	128 MB-256 MB	512 MB	1 GB-32 GB
Maximum AU Size	512 KB	1 MB	2 MB	4 MB

**ERASE\_SIZE**

This 16-bit field indicates NERASE. When NERASE numbers of AUs are erased, the timeout value is specified by ERASE\_TIMEOUT (Refer to [ERASE\\_TIMEOUT](#)). The host should determine the proper number of AUs to be erased in one operation so that the host can show the progress of the erase operation. If this field is set to 0, the erase timeout calculation is not supported.

**Table 108. Erase size field**

ERASE_SIZE	Value definition
0000h	Erase timeout calculation is not supported.
0001h	1 AU
0002h	2 AU
0003h	3 AU
-----	-----
FFFFh	65535 AU

## ERASE\_TIMEOUT

This 6-bit field indicates T<sub>ERASE</sub> and the value indicates the erase timeout from offset when multiple AUs are being erased as specified by ERASE\_SIZE. The range of ERASE\_TIMEOUT can be defined as up to 63 seconds and the card manufacturer can choose any combination of ERASE\_SIZE and ERASE\_TIMEOUT depending on the implementation. Determining ERASE\_TIMEOUT determines the ERASE\_SIZE.

**Table 109. Erase timeout field**

ERASE_TIMEOUT	Value definition
00	Erase timeout calculation is not supported.
01	1 [sec]
02	2 [sec]
03	3 [sec]
-----	-----
63	63 [sec]

## ERASE\_OFFSET

This 2-bit field indicates T<sub>OFFSET</sub> and one of four values can be selected. This field is meaningless if the ERASE\_SIZE and ERASE\_TIMEOUT fields are set to 0.

**Table 110. Erase offset field**

ERASE_OFFSET	Value definition
0h	0 [sec]
1h	1 [sec]
2h	2 [sec]
3h	3 [sec]

### 21.4.13 SD I/O mode

#### SD I/O interrupts

To allow the SD I/O card to interrupt the MultiMediaCard/SD module, an interrupt function is available on a pin on the SD interface. Pin 8, used as SDIO\_D1 when operating in the 4-bit SD mode, signals the cards interrupt to the MultiMediaCard/SD module. The use of the interrupt is optional for each card or function within a card. The SD I/O interrupt is level-sensitive, which means that the interrupt line must be held active (low) until it is either recognized and acted upon by the MultiMediaCard/SD module or deasserted due to the end of the interrupt period. After the MultiMediaCard/SD module has serviced the interrupt, the interrupt status bit is cleared via an I/O write to the appropriate bit in the SD I/O card's internal registers. The interrupt output of all SD I/O cards is active low and the application must provide external pull-up resistors on all data lines (SDIO\_D[3:0]). The MultiMediaCard/SD module samples the level of pin 8 (SDIO\_D/IRQ) into the interrupt detector only during the interrupt period. At all other times, the MultiMediaCard/SD module ignores this value.

The interrupt period is applicable for both memory and I/O operations. The definition of the interrupt period for operations with single blocks is different from the definition for multiple-block data transfers.

### SD I/O suspend and resume

Within a multifunction SD I/O or a card with both I/O and memory functions, there are multiple devices (I/O and memory) that share access to the MMC/SD bus. To share access to the MMC/SD module among multiple devices, SD I/O and combo cards optionally implement the concept of suspend/resume. When a card supports suspend/resume, the MMC/SD module can temporarily halt a data transfer operation to one function or memory (suspend) to free the bus for a higher-priority transfer to a different function or memory. After this higher-priority transfer is complete, the original transfer is resumed (restarted) where it left off. Support of suspend/resume is optional on a per-card basis. To perform the suspend/resume operation on the MMC/SD bus, the MMC/SD module performs the following steps:

1. Determines the function currently using the SDIO\_D [3:0] line(s)
2. Requests the lower-priority or slower transaction to suspend
3. Waits for the transaction suspension to complete
4. Begins the higher-priority transaction
5. Waits for the completion of the higher priority transaction
6. Restores the suspended transaction

### SD I/O ReadWait

The optional ReadWait (RW) operation is defined only for the SD 1-bit and 4-bit modes. The ReadWait operation allows the MMC/SD module to signal a card that it is reading multiple registers (IO\_RW\_EXTENDED, CMD53) to temporarily stall the data transfer while allowing the MMC/SD module to send commands to any function within the SD I/O device. To determine when a card supports the ReadWait protocol, the MMC/SD module must test capability bits in the internal card registers. The timing for ReadWait is based on the interrupt period.

## 21.4.14 Commands and responses

### Application-specific and general commands

The SD card host module system is designed to provide a standard interface for a variety of applications types. In this environment, there is a need for specific customer/application features. To implement these features, two types of generic commands are defined in the standard: application-specific commands (ACMD) and general commands (GEN\_CMD).

When the card receives the APP\_CMD (CMD55) command, the card expects the next command to be an application-specific command. ACMDs have the same structure as regular MultiMediaCard commands and can have the same CMD number. The card recognizes it as ACMD because it appears after APP\_CMD (CMD55). When the command immediately following the APP\_CMD (CMD55) is not a defined application-specific command, the standard command is used. For example, when the card has a definition for SD\_STATUS (ACMD13), and receives CMD13 immediately following APP\_CMD (CMD55), this is interpreted as SD\_STATUS (ACMD13). However, when the card receives CMD7 immediately following APP\_CMD (CMD55) and the card does not have a definition for ACMD7, this is interpreted as the standard (SELECT/DESELECT\_CARD) CMD7.

To use one of the manufacturer-specific ACMDs the SD card Host must perform the following steps:

1. Send APP\_CMD (CMD55)  
The card responds to the MultiMediaCard/SD module, indicating that the APP\_CMD bit is set and an ACMD is now expected.
2. Send the required ACMD  
The card responds to the MultiMediaCard/SD module, indicating that the APP\_CMD bit is set and that the accepted command is interpreted as an ACMD. When a nonACMD is sent, it is handled by the card as a normal MultiMediaCard command and the APP\_CMD bit in the card status register stays clear.

When an invalid command is sent (neither ACMD nor CMD) it is handled as a standard MultiMediaCard illegal command error.

The bus transaction for a GEN\_CMD is the same as the single-block read or write commands (WRITE\_BLOCK, CMD24 or READ\_SINGLE\_BLOCK, CMD17). In this case, the argument denotes the direction of the data transfer rather than the address, and the data block has vendor-specific format and meaning.

The card must be selected (in transfer state) before sending GEN\_CMD (CMD56). The data block size is defined by SET\_BLOCKLEN (CMD16). The response to GEN\_CMD (CMD56) is in R1b format.

### Command types

Both application-specific and general commands are divided into the four following types:

- **broadcast command (BC):** sent to all cards; no responses returned.
- **broadcast command with response (BCR):** sent to all cards; responses received from all cards simultaneously.
- **addressed (point-to-point) command (AC):** sent to the card that is selected; does not include a data transfer on the SDIO\_D line(s).
- **addressed (point-to-point) data transfer command (ADTC):** sent to the card that is selected; includes a data transfer on the SDIO\_D line(s).

### Command formats

See [Table 95 on page 615](#) for command formats.

### Commands for the MultiMediaCard/SD module

**Table 111. Block-oriented write commands**

CMD index	Type	Argument	Response format	Abbreviation	Description
CMD23	ac	[31:16] set to 0 [15:0] number of blocks	R1	SET_BLOCK_COUNT	Defines the number of blocks which are going to be transferred in the multiple-block read or write command that follows.
CMD24	adtc	[31:0] data address	R1	WRITE_BLOCK	Writes a block of the size selected by the SET_BLOCKLEN command.

Table 111. Block-oriented write commands (continued)

CMD index	Type	Argument	Response format	Abbreviation	Description
CMD25	adtc	[31:0] data address	R1	WRITE_MULTIPLE_BLOCK	Continuously writes blocks of data until a STOP_TRANSMISSION follows or the requested number of blocks has been received.
CMD26	adtc	[31:0] stuff bits	R1	PROGRAM_CID	Programming of the card identification register. This command must be issued only once per card. The card contains hardware to prevent this operation after the first programming. Normally this command is reserved for manufacturer.
CMD27	adtc	[31:0] stuff bits	R1	PROGRAM_CSD	Programming of the programmable bits of the CSD.

Table 112. Block-oriented write protection commands

CMD index	Type	Argument	Response format	Abbreviation	Description
CMD28	ac	[31:0] data address	R1b	SET_WRITE_PROT	If the card has write protection features, this command sets the write protection bit of the addressed group. The properties of write protection are coded in the card-specific data (WP_GRP_SIZE).
CMD29	ac	[31:0] data address	R1b	CLR_WRITE_PROT	If the card provides write protection features, this command clears the write protection bit of the addressed group.
CMD30	adtc	[31:0] write protect data address	R1	SEND_WRITE_PROT	If the card provides write protection features, this command asks the card to send the status of the write protection bits.
CMD31	Reserved				

Table 113. Erase commands

CMD index	Type	Argument	Response format	Abbreviation	Description
CMD32 ... CMD34	Reserved. These command indexes cannot be used in order to maintain backward compatibility with older versions of the MultiMediaCard.				
CMD35	ac	[31:0] data address	R1	ERASE_GROUP_START	Sets the address of the first erase group within a range to be selected for erase.
CMD36	ac	[31:0] data address	R1	ERASE_GROUP_END	Sets the address of the last erase group within a continuous range to be selected for erase.

Table 113. Erase commands (continued)

CMD index	Type	Argument	Response format	Abbreviation	Description
CMD37	Reserved. This command index cannot be used in order to maintain backward compatibility with older versions of the MultiMediaCards				
CMD38	ac	[31:0] stuff bits	R1	ERASE	Erases all previously selected write blocks.

Table 114. I/O mode commands

CMD index	Type	Argument	Response format	Abbreviation	Description
CMD39	ac	[31:16] RCA [15:15] register write flag [14:8] register address [7:0] register data	R4	FAST_IO	Used to write and read 8-bit (register) data fields. The command addresses a card and a register and provides the data for writing if the write flag is set. The R4 response contains data read from the addressed register. This command accesses application-dependent registers that are not defined in the MultiMediaCard standard.
CMD40	bcr	[31:0] stuff bits	R5	GO_IRQ_STATE	Places the system in the interrupt mode.
CMD41	Reserved				

Table 115. Lock card

CMD index	Type	Argument	Response format	Abbreviation	Description
CMD42	adtc	[31:0] stuff bits	R1b	LOCK_UNLOCK	Sets/resets the password or locks/unlocks the card. The size of the data block is set by the SET_BLOCK_LEN command.
CMD43 ... CMD54	Reserved				

Table 116. Application-specific commands

CMD index	Type	Argument	Response format	Abbreviation	Description
CMD55	ac	[31:16] RCA [15:0] stuff bits	R1	APP_CMD	Indicates to the card that the next command bits is an application specific command rather than a standard command
CMD56	adtc	[31:1] stuff bits [0]: RD/WR			Used either to transfer a data block to the card or to get a data block from the card for general purpose/application-specific commands. The size of the data block shall be set by the SET_BLOCK_LEN command.

Table 116. Application-specific commands (continued)

CMD index	Type	Argument	Response format	Abbreviation	Description
CMD57 ... CMD59	Reserved.				
CMD60 ... CMD63	Reserved for manufacturer.				

## 21.5 Response formats

All responses are sent via the MCCMD command line SDIO\_CMD. The response transmission always starts with the left bit of the bit string corresponding to the response code word. The code length depends on the response type.

A response always starts with a start bit (always 0), followed by the bit indicating the direction of transmission (card = 0). A value denoted by x in the tables below indicates a variable entry. All responses, except for the R3 response type, are protected by a CRC. Every command code word is terminated by the end bit (always 1).

There are five types of responses. Their formats are defined as follows:

### 21.5.1 R1 (normal response command)

Code length = 48 bits. The 45:40 bits indicate the index of the command to be responded to, this value being interpreted as a binary-coded number (between 0 and 63). The status of the card is coded in 32 bits.

Table 117. R1 response

Bit position	Width (bits)	Value	Description
47	1	0	Start bit
46	1	0	Transmission bit
[45:40]	6	X	Command index
[39:8]	32	X	Card status
[7:1]	7	X	CRC7
0	1	1	End bit

### 21.5.2 R1b

It is identical to R1 with an optional busy signal transmitted on the data line. The card may become busy after receiving these commands based on its state prior to the command reception.

### 21.5.3 R2 (CID, CSD register)

Code length = 136 bits. The contents of the CID register are sent as a response to the CMD2 and CMD10 commands. The contents of the CSD register are sent as a response to

CMD9. Only the bits [127...1] of the CID and CSD are transferred, the reserved bit [0] of these registers is replaced by the end bit of the response. The card indicates that an erase is in progress by holding MCDAT low. The actual erase time may be quite long, and the host may issue CMD7 to deselect the card.

**Table 118. R2 response**

Bit position	Width (bits)	Value	Description
135	1	0	Start bit
134	1	0	Transmission bit
[133:128]	6	'111111'	Command index
[127:1]	127	X	Card status
0	1	1	End bit

### 21.5.4 R3 (OCR register)

Code length: 48 bits. The contents of the OCR register are sent as a response to CMD1. The level coding is as follows: restricted voltage windows = low, card busy = low.

**Table 119. R3 response**

Bit position	Width (bits)	Value	Description
47	1	0	Start bit
46	1	0	Transmission bit
[45:40]	6	'111111'	Reserved
[39:8]	32	X	OCR register
[7:1]	7	'1111111'	Reserved
0	1	1	End bit

### 21.5.5 R4 (Fast I/O)

Code length: 48 bits. The argument field contains the RCA of the addressed card, the register address to be read from or written to, and its content.

**Table 120. R4 response**

Bit position	Width (bits)	Value	Description	
47	1	0	Start bit	
46	1	0	Transmission bit	
[45:40]	6	'100111'	CMD39	
[39:8] Argument field	[31:16]	16	X	RCA
	[15:8]	8	X	register address
	[7:0]	8	X	read register contents



Table 120. R4 response (continued)

Bit position	Width (bits)	Value	Description
[7:1]	7	X	CRC7
0	1	1	End bit

### 21.5.6 R4b

For SD I/O only: an SDIO card receiving the CMD5 will respond with a unique SDIO response R4. The format is:

Table 121. R4b response

Bit position	Width (bits)	Value	Description	
47	1	0	Start bit	
46	1	0	Transmission bit	
[45:40]	6	x	Reserved	
[39:8] Argument field	39	16	X	Card is ready
	[38:36]	3	X	Number of I/O functions
	35	1	X	Present memory
	[34:32]	3	X	Stuff bits
	[31:8]	24	X	I/O ORC
[7:1]	7	X	Reserved	
0	1	1	End bit	

Once an SD I/O card has received a CMD5, the I/O portion of that card is enabled to respond normally to all further commands. This I/O enable of the function within the I/O card will remain set until a reset, power cycle or CMD52 with write to I/O reset is received by the card. Note that an SD memory-only card may respond to a CMD5. The proper response for a memory-only card would be *Present memory* = 1 and *Number of I/O functions* = 0. A memory-only card built to meet the SD Memory Card specification version 1.0 would detect the CMD5 as an illegal command and not respond. The I/O aware host will send CMD5. If the card responds with response R4, the host determines the card's configuration based on the data contained within the R4 response.

### 21.5.7 R5 (interrupt request)

Only for MultiMediaCard. Code length: 48 bits. If the response is generated by the host, the RCA field in the argument will be 0x0.

Table 122. R5 response

Bit position	Width (bits)	Value	Description
47	1	0	Start bit
46	1	0	Transmission bit
[45:40]	6	'101000'	CMD40

**Table 122. R5 response (continued)**

Bit position		Width (bits)	Value	Description
[39:8] Argument field	[31:16]	16	X	RCA [31:16] of winning card or of the host
	[15:0]	16	X	Not defined. May be used for IRQ data
[7:1]		7	X	CRC7
0		1	1	End bit

**21.5.8 R6**

Only for SD I/O. The normal response to CMD3 by a memory device. It is shown in [Table 123](#).

**Table 123. R6 response**

Bit position		Width (bits)	Value	Description
47		1	0	Start bit
46		1	0	Transmission bit
[45:40]		6	'101000'	CMD40
[39:8] Argument field	[31:16]	16	X	RCA [31:16] of winning card or of the host
	[15:0]	16	X	Not defined. May be used for IRQ data
[7:1]		7	X	CRC7
0		1	1	End bit

The card [23:8] status bits are changed when CMD3 is sent to an I/O-only card. In this case, the 16 bits of response are the SD I/O-only values:

- Bit [15] COM\_CRC\_ERROR
- Bit [14] ILLEGAL\_COMMAND
- Bit [13] ERROR
- Bits [12:0] Reserved

**21.6 SDIO I/O card-specific operations**

The following features are SD I/O-specific operations:

- SDIO read wait operation by SDIO\_D2 signalling
- SDIO read wait operation by stopping the clock
- SDIO suspend/resume operation (write and read suspend)
- SDIO interrupts

The SDIO supports these operations only if the SDIO\_DCTRL[11] bit is set, except for read suspend that does not need specific hardware implementation.

### 21.6.1 SDIO I/O read wait operation by SDIO\_D2 signaling

It is possible to start the readwait interval before the first block is received: when the data path is enabled (SDIO\_DCTRL[0] bit set), the SDIO-specific operation is enabled (SDIO\_DCTRL[11] bit set), read wait starts (SDIO\_DCTRL[10] =0 and SDI\_DCTRL[8] =1) and data direction is from card to SDIO (SDIO\_DCTRL[1] = 1), the DPSM directly moves from Idle to Readwait. In Readwait the DPSM drives SDIO\_D2 to 0 after 2 SDIO\_CK clock cycles. In this state, when you set the RWSTOP bit (SDIO\_DCTRL[9]), the DPSM remains in Wait for two more SDIO\_CK clock cycles to drive SDIO\_D2 to 1 for one clock cycle (in accordance with SDIO specification). The DPSM then starts waiting again until it receives data from the card. The DPSM will not start a readwait interval while receiving a block even if read wait start is set: the readwait interval will start after the CRC is received. The RWSTOP bit has to be cleared to start a new read wait operation. During the readwait interval, the SDIO can detect SDIO interrupts on SDIO\_D1.

### 21.6.2 SDIO read wait operation by stopping SDIO\_CK

If the SDIO card does not support the previous read wait method, the SDIO can perform a read wait by stopping SDIO\_CK (SDIO\_DCTRL is set just like in the method presented in [Section 21.6.1](#), but SDIO\_DCTRL[10] =1): DPSM stops the clock two SDIO\_CK cycles after the end bit of the current received block and starts the clock again after the read wait start bit is set.

As SDIO\_CK is stopped, any command can be issued to the card. During a read/wait interval, the SDIO can detect SDIO interrupts on SDIO\_D1.

### 21.6.3 SDIO suspend/resume operation

While sending data to the card, the SDIO can suspend the write operation. the SDIO\_CMD[11] bit is set and indicates to the CPSM that the current command is a suspend command. The CPSM analyzes the response and when the ACK is received from the card (suspend accepted), it acknowledges the DPSM that goes Idle after receiving the CRC token of the current block.

The hardware does not save the number of the remaining block to be sent to complete the suspended operation (resume).

The write operation can be suspended by software, just by disabling the DPSM (SDIO\_DCTRL[0] =0) when the ACK of the suspend command is received from the card. The DPSM enters then the Idle state.

To suspend a read: the DPSM waits in the Wait\_r state as the function to be suspended sends a complete packet just before stopping the data transaction. The application continues reading RxFIFO until the FIFO is empty, and the DPSM goes Idle automatically.

### 21.6.4 SDIO interrupts

SDIO interrupts are detected on the SDIO\_D1 line once the SDIO\_DCTRL[11] bit is set.

## 21.7 CE-ATA specific operations

The following features are CE-ATA specific operations:

- sending the command completion signal disable to the CE-ATA device
- receiving the command completion signal from the CE-ATA device
- signaling the completion of the CE-ATA command to the CPU, using the status bit and/or interrupt.

The SDIO supports these operations only for the CE-ATA CMD61 command, that is, if SDIO\_CMD[14] is set.

### 21.7.1 Command completion signal disable

Command completion signal disable is sent 8 bit cycles after the reception of a **short** response if the 'enable CMD completion' bit, SDIO\_CMD[12], is not set and the 'not interrupt Enable' bit, SDIO\_CMD[13], is set.

The CPSM enters the Pend state, loading the command shift register with the disable sequence "00001" and, the command counter with 43. Eight cycles after, a trigger moves the CPSM to the Send state. When the command counter reaches 48, the CPSM becomes Idle as no response is awaited.

### 21.7.2 Command completion signal enable

If the 'enable CMD completion' bit SDIO\_CMD[12] is set and the 'not interrupt Enable' bit SDIO\_CMD[13] is set, the CPSM waits for the command completion signal in the Waitcpl state.

When '0' is received on the CMD line, the CPSM enters the Idle state. No new command can be sent for 7 bit cycles. Then, for the last 5 cycles (out of the 7) the CMD line is driven to '1' in push-pull mode.

### 21.7.3 CE-ATA interrupt

The command completion is signaled to the CPU by the status bit SDIO\_STA[23]. This static bit can be cleared with the clear bit SDIO\_ICR[23].

The SDIO\_STA[23] status bit can generate an interrupt on each interrupt line, depending on the mask bit SDIO\_MASKx[23].

### 21.7.4 Aborting CMD61

If the command completion disable signal has not been sent and CMD61 needs to be aborted, the command state machine must be disabled. It then becomes Idle, and the CMD12 command can be sent. No command completion disable signal is sent during the operation.

## 21.8 HW flow control

The HW flow control functionality is used to avoid FIFO underrun (TX mode) and overrun (RX mode) errors.

The behavior is to stop SDIO\_CK and freeze SDIO state machines. The data transfer is stalled while the FIFO is unable to transmit or receive data. Only state machines clocked by SDIOCLK are frozen, the APB2 interface is still alive. The FIFO can thus be filled or emptied even if flow control is activated.

To enable HW flow control, the SDIO\_CLKCR[14] register bit must be set to 1. After reset Flow Control is disabled.

## 21.9 SDIO registers

The device communicates to the system via 32-bit-wide control registers accessible via APB2.

The peripheral registers have to be accessed by words (32 bits).

### 21.9.1 SDIO power control register (SDIO\_POWER)

Address offset: 0x00

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved																PWRC TRL															
																rw	rw														

Bits 31:2 Reserved, must be kept at reset value

Bits 1:0 **PWRCTRL**: Power supply control bits.

These bits are used to define the current functional state of the card clock:

00: Power-off: the clock to card is stopped.

01: Reserved

10: Reserved power-up

11: Power-on: the card is clocked.

*Note:* At least seven HCLK clock periods are needed between two write accesses to this register. After a data write, data cannot be written to this register for three SDIOCLK (48 MHz) clock periods plus two PCLK2 clock periods.

### 21.9.2 SDI clock control register (SDIO\_CLKCR)

Address offset: 0x04

Reset value: 0x0000 0000

The SDIO\_CLKCR register controls the SDIO\_CK output clock.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0														
Reserved															HWFC_EN	NEGEDGE	WID BUS		BYPASS	PWRS AV	CLKEN	CLKDIV																							
															rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 31:15 Reserved, must be kept at reset value

Bit 14 **HWFC\_EN**: HW Flow Control enable

- 0b: HW Flow Control is disabled
- 1b: HW Flow Control is enabled

When HW Flow Control is enabled, the meaning of the TXFIFOE and RXFIFOE interrupt signals, please see SDIO Status register definition in [Section 21.9.11](#).

Bit 13 **NEGEDGE**:SDIO\_CK dephasing selection bit

- 0b: SDIO\_CK generated on the rising edge of the master clock SDIOCLK
- 1b: SDIO\_CK generated on the falling edge of the master clock SDIOCLK

Bits 12:11 **WIDBUS**: Wide bus mode enable bit

- 00: Default bus mode: SDIO\_D0 used
- 01: 4-wide bus mode: SDIO\_D[3:0] used
- 10: 8-wide bus mode: SDIO\_D[7:0] used

Bit 10 **BYPASS**: Clock divider bypass enable bit

- 0: Disable bypass: SDIOCLK is divided according to the CLKDIV value before driving the SDIO\_CK output signal.
- 1: Enable bypass: SDIOCLK directly drives the SDIO\_CK output signal.

Bit 9 **PWRS AV**: Power saving configuration bit

- For power saving, the SDIO\_CK clock output can be disabled when the bus is idle by setting PWRS AV:
- 0: SDIO\_CK clock is always enabled
- 1: SDIO\_CK is only enabled when the bus is active

Bit 8 **CLKEN**: Clock enable bit

- 0: SDIO\_CK is disabled
- 1: SDIO\_CK is enabled

Bits 7:0 **CLKDIV**: Clock divide factor

This field defines the divide factor between the input clock (SDIOCLK) and the output clock (SDIO\_CK): SDIO\_CK frequency = SDIOCLK / [CLKDIV + 2].

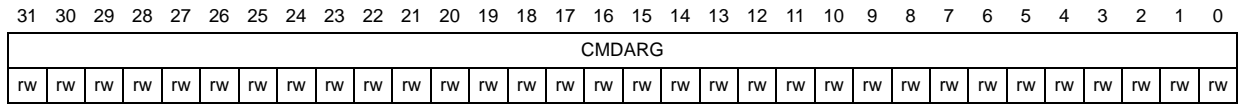
*Note:* While the SD/SDIO card or MultiMediaCard is in identification mode, the SDIO\_CK frequency must be less than 400 kHz.  
 The clock frequency can be changed to the maximum card bus frequency when relative card addresses are assigned to all cards.  
 After a data write, data cannot be written to this register for three SDIOCLK (48 MHz) clock periods plus two PCLK2 clock periods. SDIO\_CK can also be stopped during the read wait interval for SD I/O cards: in this case the SDIO\_CLKCR register does not control SDIO\_CK.

**21.9.3 SDIO argument register (SDIO\_ARG)**

Address offset: 0x08

Reset value: 0x0000 0000

The SDIO\_ARG register contains a 32-bit command argument, which is sent to a card as part of a command message.



Bits 31:0 **CMDARG:** Command argument

Command argument sent to a card as part of a command message. If a command contains an argument, it must be loaded into this register before writing a command to the command register.

### 21.9.4 SDIO command register (SDIO\_CMD)

Address offset: 0x0C

Reset value: 0x0000 0000

The SDIO\_CMD register contains the command index and command type bits. The command index is sent to a card as part of a command message. The command type bits control the command path state machine (CPSM).

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0													
Reserved																	CE-ATACMD	nIEN	ENCMDcompl	SDIOSuspend	CPSMEN	WAITPEND	WAITINT	WAITRESP	CMDINDEX																			
																	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 31:15 Reserved, must be kept at reset value

Bit 14 **ATACMD**: CE-ATA command

If ATACMD is set, the CPSM transfers CMD61.

Bit 13 **nIEN**: not Interrupt Enable

if this bit is 0, interrupts in the CE-ATA device are enabled.

Bit 12 **ENCMDcompl**: Enable CMD completion

If this bit is set, the command completion signal is enabled.

Bit 11 **SDIOSuspend**: SD I/O suspend command

If this bit is set, the command to be sent is a suspend command (to be used only with SDIO card).

Bit 10 **CPSMEN**: Command path state machine (CPSM) Enable bit

If this bit is set, the CPSM is enabled.

Bit 9 **WAITPEND**: CPSM Waits for ends of data transfer (CmdPend internal signal).

If this bit is set, the CPSM waits for the end of data transfer before it starts sending a command.

Bit 8 **WAITINT**: CPSM waits for interrupt request

If this bit is set, the CPSM disables command timeout and waits for an interrupt request.

Bits 7:6 **WAITRESP**: Wait for response bits

They are used to configure whether the CPSM is to wait for a response, and if yes, which kind of response.

00: No response, expect CMDSENT flag

01: Short response, expect CMDREND or CCRCFAIL flag

10: No response, expect CMDSENT flag

11: Long response, expect CMDREND or CCRCFAIL flag

Bits 5:0 **CMDINDEX**: Command index

The command index is sent to the card as part of a command message.

*Note:* After a data write, data cannot be written to this register for three SDIOCLK (48 MHz) clock periods plus two PCLK2 clock periods.

MultiMediaCards can send two kinds of response: short responses, 48 bits long, or long responses, 136 bits long. SD card and SD I/O card can send only short responses, the





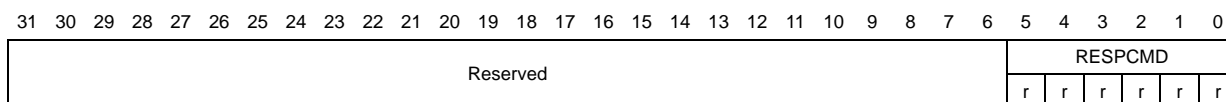
argument can vary according to the type of response: the software will distinguish the type of response according to the sent command. CE-ATA devices send only short responses.

### 21.9.5 SDIO command response register (SDIO\_RESPCMD)

Address offset: 0x10

Reset value: 0x0000 0000

The SDIO\_RESPCMD register contains the command index field of the last command response received. If the command response transmission does not contain the command index field (long or OCR response), the RESPCMD field is unknown, although it must contain 111111b (the value of the reserved field from the response).



Bits 31:6 Reserved, must be kept at reset value

Bits 5:0 **RESPCMD**: Response command index

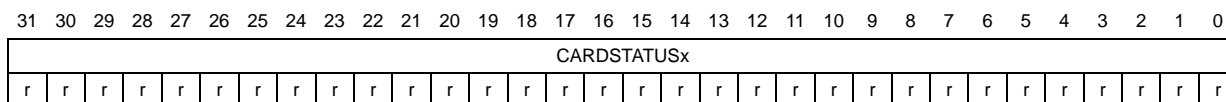
Read-only bit field. Contains the command index of the last command response received.

### 21.9.6 SDIO response 1..4 register (SDIO\_RESPx)

Address offset: (0x10 + (4 × x)); x = 1..4

Reset value: 0x0000 0000

The SDIO\_RESP1/2/3/4 registers contain the status of a card, which is part of the received response.



Bits 31:0 **CARDSTATUSx**: see [Table 124](#).

The Card Status size is 32 or 127 bits, depending on the response type.

**Table 124. Response type and SDIO\_RESPx registers**

Register	Short response	Long response
SDIO_RESP1	Card Status[31:0]	Card Status [127:96]
SDIO_RESP2	Unused	Card Status [95:64]
SDIO_RESP3	Unused	Card Status [63:32]
SDIO_RESP4	Unused	Card Status [31:1]0b

The most significant bit of the card status is received first. The SDIO\_RESP3 register LSB is always 0b.

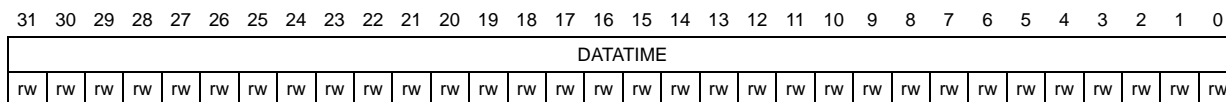
### 21.9.7 SDIO data timer register (SDIO\_DTIMER)

Address offset: 0x24

Reset value: 0x0000 0000

The SDIO\_DTIMER register contains the data timeout period, in card bus clock periods.

A counter loads the value from the SDIO\_DTIMER register, and starts decrementing when the data path state machine (DPSM) enters the Wait\_R or Busy state. If the timer reaches 0 while the DPSM is in either of these states, the timeout status flag is set.



Bits 31:0 **DATATIME**: Data timeout period  
 Data timeout period expressed in card bus clock periods.

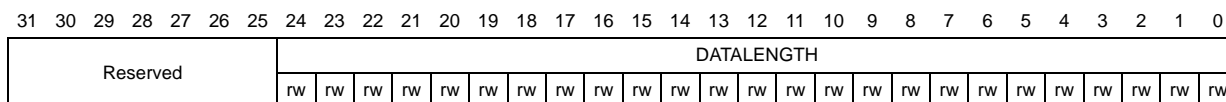
*Note:* A data transfer must be written to the data timer register and the data length register before being written to the data control register.

### 21.9.8 SDIO data length register (SDIO\_DLEN)

Address offset: 0x28

Reset value: 0x0000 0000

The SDIO\_DLEN register contains the number of data bytes to be transferred. The value is loaded into the data counter when data transfer starts.



Bits 31:25 Reserved, must be kept at reset value

Bits 24:0 **DATALENGTH**: Data length value  
 Number of data bytes to be transferred.

*Note:* For a block data transfer, the value in the data length register must be a multiple of the block size (see SDIO\_DCTRL). A data transfer must be written to the data timer register and the data length register before being written to the data control register.  
 For an SDIO multibyte transfer the value in the data length register must be between 1 and 512.

### 21.9.9 SDIO data control register (SDIO\_DCTRL)

Address offset: 0x2C

Reset value: 0x0000 0000

The SDIO\_DCTRL register control the data path state machine (DPSM).

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0																					
Reserved																				SDIOEN	RWMOD	RWSTOP	RWSTART	DBLOCKSIZE				DMAEN	DTMODE	DTDIR	DTEN																					
																				rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 31:12 Reserved, must be kept at reset value

Bit 11 **SDIOEN**: SD I/O enable functions

If this bit is set, the DPSM performs an SD I/O-card-specific operation.

Bit 10 **RWMOD**: Read wait mode

0: Read Wait control stopping SDIO\_D2

1: Read Wait control using SDIO\_CK

Bit 9 **RWSTOP**: Read wait stop

0: Read wait in progress if RWSTART bit is set

1: Enable for read wait stop if RWSTART bit is set

Bit 8 **RWSTART**: Read wait start

If this bit is set, read wait operation starts.

Bits 7:4 **DBLOCKSIZE**: Data block size

Define the data block length when the block data transfer mode is selected:

0000: (0 decimal) lock length =  $2^0 = 1$  byte

0001: (1 decimal) lock length =  $2^1 = 2$  bytes

0010: (2 decimal) lock length =  $2^2 = 4$  bytes

0011: (3 decimal) lock length =  $2^3 = 8$  bytes

0100: (4 decimal) lock length =  $2^4 = 16$  bytes

0101: (5 decimal) lock length =  $2^5 = 32$  bytes

0110: (6 decimal) lock length =  $2^6 = 64$  bytes

0111: (7 decimal) lock length =  $2^7 = 128$  bytes

1000: (8 decimal) lock length =  $2^8 = 256$  bytes

1001: (9 decimal) lock length =  $2^9 = 512$  bytes

1010: (10 decimal) lock length =  $2^{10} = 1024$  bytes

1011: (11 decimal) lock length =  $2^{11} = 2048$  bytes

1100: (12 decimal) lock length =  $2^{12} = 4096$  bytes

1101: (13 decimal) lock length =  $2^{13} = 8192$  bytes

1110: (14 decimal) lock length =  $2^{14} = 16384$  bytes

1111: (15 decimal) reserved

Bit 3 **DMAEN**: DMA enable bit

0: DMA disabled.

1: DMA enabled.



### 21.9.11 SDIO status register (SDIO\_STA)

Address offset: 0x34

Reset value: 0x0000 0000

The SDIO\_STA register is a read-only register. It contains two types of flag:

- Static flags (bits [23:22,10:0]): these bits remain asserted until they are cleared by writing to the SDIO Interrupt Clear register (see SDIO\_ICR)
- Dynamic flags (bits [21:11]): these bits change state depending on the state of the underlying logic (for example, FIFO full and empty flags are asserted and deasserted as data while written to the FIFO)

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0				
Reserved								CEATAEND	SDIOIT	RXDAVL	TXDAVL	RXFIFOE	TXFIFOE	RXFIFO	TXFIFO	RXFIFOH	TXFIFOHE	RXACT	TXACT	CMDACT	DBCKEND	STBITERR	DATAEND	CMDSENT	CMDREND	RXOVERR	TXUNDERR	DTIMEOUT	CTIMEOUT	DCRCFAIL	CCRCFAIL				
								r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r

Bits 31:24 Reserved, must be kept at reset value

Bit 23 **CEATAEND**: CE-ATA command completion signal received for CMD61

Bit 22 **SDIOIT**: SDIO interrupt received

Bit 21 **RXDAVL**: Data available in receive FIFO

Bit 20 **TXDAVL**: Data available in transmit FIFO

Bit 19 **RXFIFOE**: Receive FIFO empty

Bit 18 **TXFIFOE**: Transmit FIFO empty

When HW Flow Control is enabled, TXFIFOE signals becomes activated when the FIFO contains 2 words.

Bit 17 **RXFIFO**: Receive FIFO full

When HW Flow Control is enabled, RXFIFO signals becomes activated 2 words before the FIFO is full.

Bit 16 **TXFIFO**: Transmit FIFO full

Bit 15 **RXFIFOH**: Receive FIFO half full: there are at least 8 words in the FIFO

Bit 14 **TXFIFOHE**: Transmit FIFO half empty: at least 8 words can be written into the FIFO

Bit 13 **RXACT**: Data receive in progress

Bit 12 **TXACT**: Data transmit in progress

Bit 11 **CMDACT**: Command transfer in progress

Bit 10 **DBCKEND**: Data block sent/received (CRC check passed)

Bit 9 **STBITERR**: Start bit not detected on all data signals in wide bus mode

Bit 8 **DATAEND**: Data end (data counter, SDIDCOUNT, is zero)

Bit 7 **CMDSENT**: Command sent (no response required)

Bit 6 **CMDREND**: Command response received (CRC check passed)

Bit 5 **RXOVERR**: Received FIFO overrun error

- Bit 4 **TXUNDERR**: Transmit FIFO underrun error
- Bit 3 **DTIMEOUT**: Data timeout
- Bit 2 **CTIMEOUT**: Command response timeout  
The Command TimeOut period has a fixed value of 64 SDIO\_CK clock periods.
- Bit 1 **DCRCFAIL**: Data block sent/received (CRC check failed)
- Bit 0 **CCRCFAIL**: Command response received (CRC check failed)

### 21.9.12 SDIO interrupt clear register (SDIO\_ICR)

Address offset: 0x38

Reset value: 0x0000 0000

The SDIO\_ICR register is a write-only register. Writing a bit with 1b clears the corresponding bit in the SDIO\_STA Status register.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0				
Reserved								CEATAENDC	SDIOITC	Reserved											DBCKENDC	STBITERRC	DATAENDC	CMDSENTC	CMDREND	RXOVERRC	TXUNDERRC	DTIMEOUTC	CTIMEOUTC	DCRCFAILC	CCRCFAILC				
								rw	rw												rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 31:24 Reserved, must be kept at reset value

- Bit 23 **CEATAENDC**: CEATAEND flag clear bit  
Set by software to clear the CEATAEND flag.  
0: CEATAEND not cleared  
1: CEATAEND cleared

- Bit 22 **SDIOITC**: SDIOIT flag clear bit  
Set by software to clear the SDIOIT flag.  
0: SDIOIT not cleared  
1: SDIOIT cleared

Bits 21:11 Reserved, must be kept at reset value

- Bit 10 **DBCKENDC**: DBCKEND flag clear bit  
Set by software to clear the DBCKEND flag.  
0: DBCKEND not cleared  
1: DBCKEND cleared

- Bit 9 **STBITERRC**: STBITERR flag clear bit  
Set by software to clear the STBITERR flag.  
0: STBITERR not cleared  
1: STBITERR cleared

- Bit 8 **DATAENDC**: DATAEND flag clear bit  
Set by software to clear the DATAEND flag.  
0: DATAEND not cleared  
1: DATAEND cleared

- Bit 7 **CMDSENTC**: CMDSENT flag clear bit  
Set by software to clear the CMDSENT flag.  
0: CMDSENT not cleared  
1: CMDSENT cleared
- Bit 6 **CMDREND C**: CMDREND flag clear bit  
Set by software to clear the CMDREND flag.  
0: CMDREND not cleared  
1: CMDREND cleared
- Bit 5 **RXOVERR C**: RXOVERR flag clear bit  
Set by software to clear the RXOVERR flag.  
0: RXOVERR not cleared  
1: RXOVERR cleared
- Bit 4 **TXUNDERR C**: TXUNDERR flag clear bit  
Set by software to clear TXUNDERR flag.  
0: TXUNDERR not cleared  
1: TXUNDERR cleared
- Bit 3 **DTIMEOUT C**: DTIMEOUT flag clear bit  
Set by software to clear the DTIMEOUT flag.  
0: DTIMEOUT not cleared  
1: DTIMEOUT cleared
- Bit 2 **CTIMEOUT C**: CTIMEOUT flag clear bit  
Set by software to clear the CTIMEOUT flag.  
0: CTIMEOUT not cleared  
1: CTIMEOUT cleared
- Bit 1 **DCRCFAIL C**: DCRCFAIL flag clear bit  
Set by software to clear the DCRCFAIL flag.  
0: DCRCFAIL not cleared  
1: DCRCFAIL cleared
- Bit 0 **CCRCFAIL C**: CCRCFAIL flag clear bit  
Set by software to clear the CCRCFAIL flag.  
0: CCRCFAIL not cleared  
1: CCRCFAIL cleared

### 21.9.13 SDIO mask register (SDIO\_MASK)

Address offset: 0x3C

Reset value: 0x0000 0000

The interrupt mask register determines which status flags generate an interrupt request by setting the corresponding bit to 1b.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved								CEATAENDIE	SDIOITIE	RXDAVLIE	TXDAVLIE	RXFIFOEIE	TXFIFOEIE	RXFIFOEIE	TXFIFOEIE	RXFIFOEIE	TXFIFOEIE	RXACTIE	TXACTIE	CMDACTIE	DBCKENDIE	STBITERRIE	DATAENDIE	CMDSENTIE	CMDRENDIE	RXOVERRIE	TXUNDERRIE	DTIMEOUTIE	CTIMEOUTIE	DCRCFAILIE	CCRCFAILIE
								r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w

Bits 31:24 Reserved, must be kept at reset value

- Bit 23 CEATAENDIE:** CE-ATA command completion signal received interrupt enable  
 Set and cleared by software to enable/disable the interrupt generated when receiving the CE-ATA command completion signal.  
 0: CE-ATA command completion signal received interrupt disabled  
 1: CE-ATA command completion signal received interrupt enabled
- Bit 22 SDIOITIE:** SDIO mode interrupt received interrupt enable  
 Set and cleared by software to enable/disable the interrupt generated when receiving the SDIO mode interrupt.  
 0: SDIO Mode Interrupt Received interrupt disabled  
 1: SDIO Mode Interrupt Received interrupt enabled
- Bit 21 RXDAVLIE:** Data available in Rx FIFO interrupt enable  
 Set and cleared by software to enable/disable the interrupt generated by the presence of data available in Rx FIFO.  
 0: Data available in Rx FIFO interrupt disabled  
 1: Data available in Rx FIFO interrupt enabled
- Bit 20 TXDAVLIE:** Data available in Tx FIFO interrupt enable  
 Set and cleared by software to enable/disable the interrupt generated by the presence of data available in Tx FIFO.  
 0: Data available in Tx FIFO interrupt disabled  
 1: Data available in Tx FIFO interrupt enabled
- Bit 19 RXFIFOEIE:** Rx FIFO empty interrupt enable  
 Set and cleared by software to enable/disable interrupt caused by Rx FIFO empty.  
 0: Rx FIFO empty interrupt disabled  
 1: Rx FIFO empty interrupt enabled
- Bit 18 TXFIFOEIE:** Tx FIFO empty interrupt enable  
 Set and cleared by software to enable/disable interrupt caused by Tx FIFO empty.  
 0: Tx FIFO empty interrupt disabled  
 1: Tx FIFO empty interrupt enabled
- Bit 17 RXFIFOEIE:** Rx FIFO full interrupt enable  
 Set and cleared by software to enable/disable interrupt caused by Rx FIFO full.  
 0: Rx FIFO full interrupt disabled  
 1: Rx FIFO full interrupt enabled





- Bit 16 **TXFIFOIE**: Tx FIFO full interrupt enable  
Set and cleared by software to enable/disable interrupt caused by Tx FIFO full.  
0: Tx FIFO full interrupt disabled  
1: Tx FIFO full interrupt enabled
- Bit 15 **RXFIFOHFIE**: Rx FIFO half full interrupt enable  
Set and cleared by software to enable/disable interrupt caused by Rx FIFO half full.  
0: Rx FIFO half full interrupt disabled  
1: Rx FIFO half full interrupt enabled
- Bit 14 **TXFIFOHEIE**: Tx FIFO half empty interrupt enable  
Set and cleared by software to enable/disable interrupt caused by Tx FIFO half empty.  
0: Tx FIFO half empty interrupt disabled  
1: Tx FIFO half empty interrupt enabled
- Bit 13 **RXACTIE**: Data receive acting interrupt enable  
Set and cleared by software to enable/disable interrupt caused by data being received (data receive acting).  
0: Data receive acting interrupt disabled  
1: Data receive acting interrupt enabled
- Bit 12 **TXACTIE**: Data transmit acting interrupt enable  
Set and cleared by software to enable/disable interrupt caused by data being transferred (data transmit acting).  
0: Data transmit acting interrupt disabled  
1: Data transmit acting interrupt enabled
- Bit 11 **CMDACTIE**: Command acting interrupt enable  
Set and cleared by software to enable/disable interrupt caused by a command being transferred (command acting).  
0: Command acting interrupt disabled  
1: Command acting interrupt enabled
- Bit 10 **DBCKENDIE**: Data block end interrupt enable  
Set and cleared by software to enable/disable interrupt caused by data block end.  
0: Data block end interrupt disabled  
1: Data block end interrupt enabled
- Bit 9 **STBITERRIE**: Start bit error interrupt enable  
Set and cleared by software to enable/disable interrupt caused by start bit error.  
0: Start bit error interrupt disabled  
1: Start bit error interrupt enabled
- Bit 8 **DATAENDIE**: Data end interrupt enable  
Set and cleared by software to enable/disable interrupt caused by data end.  
0: Data end interrupt disabled  
1: Data end interrupt enabled
- Bit 7 **CMDSSENTIE**: Command sent interrupt enable  
Set and cleared by software to enable/disable interrupt caused by sending command.  
0: Command sent interrupt disabled  
1: Command sent interrupt enabled

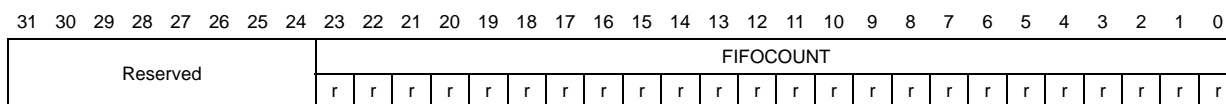
- Bit 6 **CMDRENDIE**: Command response received interrupt enable  
 Set and cleared by software to enable/disable interrupt caused by receiving command response.  
 0: Command response received interrupt disabled  
 1: command Response Received interrupt enabled
- Bit 5 **RXOVERRIE**: Rx FIFO overrun error interrupt enable  
 Set and cleared by software to enable/disable interrupt caused by Rx FIFO overrun error.  
 0: Rx FIFO overrun error interrupt disabled  
 1: Rx FIFO overrun error interrupt enabled
- Bit 4 **TXUNDERRIE**: Tx FIFO underrun error interrupt enable  
 Set and cleared by software to enable/disable interrupt caused by Tx FIFO underrun error.  
 0: Tx FIFO underrun error interrupt disabled  
 1: Tx FIFO underrun error interrupt enabled
- Bit 3 **DTIMEOUTIE**: Data timeout interrupt enable  
 Set and cleared by software to enable/disable interrupt caused by data timeout.  
 0: Data timeout interrupt disabled  
 1: Data timeout interrupt enabled
- Bit 2 **CTIMEOUTIE**: Command timeout interrupt enable  
 Set and cleared by software to enable/disable interrupt caused by command timeout.  
 0: Command timeout interrupt disabled  
 1: Command timeout interrupt enabled
- Bit 1 **DCRCFAILIE**: Data CRC fail interrupt enable  
 Set and cleared by software to enable/disable interrupt caused by data CRC failure.  
 0: Data CRC fail interrupt disabled  
 1: Data CRC fail interrupt enabled
- Bit 0 **CCRCFAILIE**: Command CRC fail interrupt enable  
 Set and cleared by software to enable/disable interrupt caused by command CRC failure.  
 0: Command CRC fail interrupt disabled  
 1: Command CRC fail interrupt enabled

### 21.9.14 SDIO FIFO counter register (SDIO\_FIFOCNT)

Address offset: 0x48

Reset value: 0x0000 0000

The SDIO\_FIFOCNT register contains the remaining number of words to be written to or read from the FIFO. The FIFO counter loads the value from the data length register (see SDIO\_DLEN) when the data transfer enable bit, DTEN, is set in the data control register (SDIO\_DCTRL register) and the DPSM is at the Idle state. If the data length is not word-aligned (multiple of 4), the remaining 1 to 3 bytes are regarded as a word.



Bits 31:24 Reserved, must be kept at reset value

Bits 23:0 **FIFOCOUNT**: Remaining number of words to be written to or read from the FIFO.

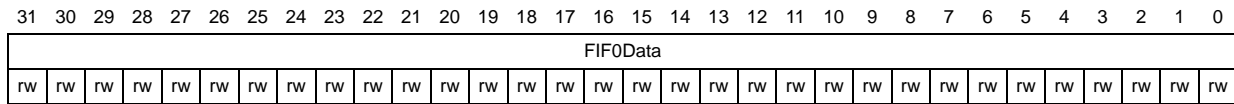


### 21.9.15 SDIO data FIFO register (SDIO\_FIFO)

Address offset: 0x80

Reset value: 0x0000 0000

The receive and transmit FIFOs can be read or written as 32-bit wide registers. The FIFOs contain 32 entries on 32 sequential addresses. This allows the CPU to use its load and store multiple operands to read from/write to the FIFO.



bits 31:0 **FIFOData**: Receive and transmit FIFO data

The FIFO data occupies 32 entries of 32-bit words, from address:  
SDIO base + 0x080 to SDIO base + 0xFC.

### 21.9.16 SDIO register map

The following table summarizes the SDIO registers.

Table 125. SDIO register map

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0x00	SDIO_POWER	Reserved																										PWRCTRL					
0x04	SDIO_CLKCR	Reserved													HWFC_EN	NEGEDGE	WIDBUS	BYPASS	PWRSV	CLKEN	CLKDIV												
0x08	SDIO_ARG	CMDARG																															
0x0C	SDIO_CMD	Reserved													CE-ATACMD	nIEN	ENCMDcompl	SDIOSuspend	CPSMEN	WAITPEND	WAITINT	WAITRESP	CMDINDEX										
0x10	SDIO_RESPCMD	Reserved																								RESPCMD							
0x14	SDIO_RESP1	CARDSTATUS1																															
0x18	SDIO_RESP2	CARDSTATUS2																															
0x1C	SDIO_RESP3	CARDSTATUS3																															
0x20	SDIO_RESP4	CARDSTATUS4																															
0x24	SDIO_DTIMER	DATATIME																															
0x28	SDIO_DLEN	Reserved						DATALENGTH																									
0x2C	SDIO_DCTRL	Reserved													SDIOEN	RWMOD	RWSTOP	RWSTART	DBLOCKSIZE				DMAEN	DTMODE	DTDIR	DTEN							
0x30	SDIO_DCOUNT	Reserved						DATACOUNT																									



Table 125. SDIO register map (continued)

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0					
0x34	SDIO_STA	Reserved								CEATAEND	SDIOIT	RXDAVL	TXDAVL	RXFIOE	TXFIOE	RXFIOF	TXFIOF	TXFIOF	RXFIOHF	TXFIOHE	RXACT	TXACT	CMDACT	DBCKEND	STBITERR	DATAEND	CMDSENT	CMDREND	RXOVERR	TXUNDERR	DTIMEOUT	CTIMEOUT	DCRCFAIL	CCRCFAIL				
0x38	SDIO_ICR	Reserved								CEATAENDC	SDIOITC	Reserved																DBCKENDC	STBITERRC	DATAENDC	CMDSENTC	CMDREND	RXOVERRC	TXUNDERRC	DTIMEOUTC	CTIMEOUTC	DCRCFAILC	CCRCFAILC
0x3C	SDIO_MASK	Reserved								CEATAENDIE	SDIOITIE	RXDAVLIE	TXDAVLIE	RXFIOEIE	TXFIOEIE	RXFIOFIE	TXFIOFIE	RXFIOHFIE	TXFIOHEIE	RXACTIE	TXACTIE	CMDACTIE	DBCKENDIE	STBITERRIE	DATAENDIE	CMDSENTIE	CMDRENDIE	RXOVERRIE	TXUNDERRIE	DTIMEOUTIE	CTIMEOUTIE	DCRCFAILIE	CCRCFAILIE					
0x48	SDIO_FIFOCNT	Reserved								FIFOCOUNT																												
0x80	SDIO_FIFO	FIFOData																																				

## 22 USB on-the-go full-speed (OTG\_FS)

### 22.1 OTG\_FS introduction

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This section presents the architecture and the programming model of the OTG\_FS controller.

The following acronyms are used throughout the section:

FS	full-speed
LS	Low-speed
MAC	Media access controller
OTG	On-the-go
PFC	Packet FIFO controller
PHY	Physical layer
USB	Universal serial bus
UTMI	USB 2.0 transceiver macrocell interface (UTMI)

References are made to the following documents:

- USB On-The-Go Supplement, Revision 1.3
- Universal Serial Bus Revision 2.0 Specification

The OTG\_FS is a dual-role device (DRD) controller that supports both device and host functions and is fully compliant with the *On-The-Go Supplement to the USB 2.0 Specification*. It can also be configured as a host-only or device-only controller, fully compliant with the *USB 2.0 Specification*. In host mode, the OTG\_FS supports full-speed (FS, 12 Mbits/s) and low-speed (LS, 1.5 Mbits/s) transfers whereas in device mode, it only supports full-speed (FS, 12 Mbits/s) transfers. The OTG\_FS supports both HNP and SRP. The only external device required is a charge pump for  $V_{BUS}$  in host mode.

### 22.2 OTG\_FS main features

The main features can be divided into three categories: general, host-mode and device-mode features.

### 22.2.1 General features

The OTG\_FS interface general features are the following:

- It is USB-IF certified to the Universal Serial Bus Specification Rev 2.0
- It includes full support (PHY) for the optional On-The-Go (OTG) protocol detailed in the On-The-Go Supplement Rev 1.3 specification
  - Integrated support for A-B Device Identification (ID line)
  - Integrated support for host Negotiation Protocol (HNP) and Session Request Protocol (SRP)
  - It allows host to turn  $V_{BUS}$  off to conserve battery power in OTG applications
  - It supports OTG monitoring of  $V_{BUS}$  levels with internal comparators
  - It supports dynamic host-peripheral switch of role
- It is software-configurable to operate as:
  - SRP capable USB FS Peripheral (B-device)
  - SRP capable USB FS/LS host (A-device)
  - USB On-The-Go Full-Speed Dual Role device
- It supports FS SOF and LS Keep-alives with
  - SOF pulse PAD connectivity
  - SOF pulse internal connection to timer2 (TIM2)
  - Configurable framing period
  - Configurable end of frame interrupt
- It includes power saving features such as system stop during USB Suspend, switch-off of clock domains internal to the digital core, PHY and DFIFO power management
- It features a dedicated RAM of 1.25 Kbytes with advanced FIFO control:
  - Configurable partitioning of RAM space into different FIFOs for flexible and efficient use of RAM
  - Each FIFO can hold multiple packets
  - Dynamic memory allocation
  - Configurable FIFO sizes that are not powers of 2 to allow the use of contiguous memory locations
- It guarantees max USB bandwidth for up to one frame (1ms) without system intervention

### 22.2.2 Host-mode features

The OTG\_FS interface main features and requirements in host-mode are the following:

- External charge pump for  $V_{BUS}$  voltage generation.
- Up to 8 host channels (pipes): each channel is dynamically reconfigurable to allocate any type of USB transfer.
- Built-in hardware scheduler holding:
  - Up to 8 interrupt plus isochronous transfer requests in the periodic hardware queue
  - Up to 8 control plus bulk transfer requests in the non-periodic hardware queue
- Management of a shared RX FIFO, a periodic TX FIFO and a nonperiodic TX FIFO for efficient usage of the USB data RAM.

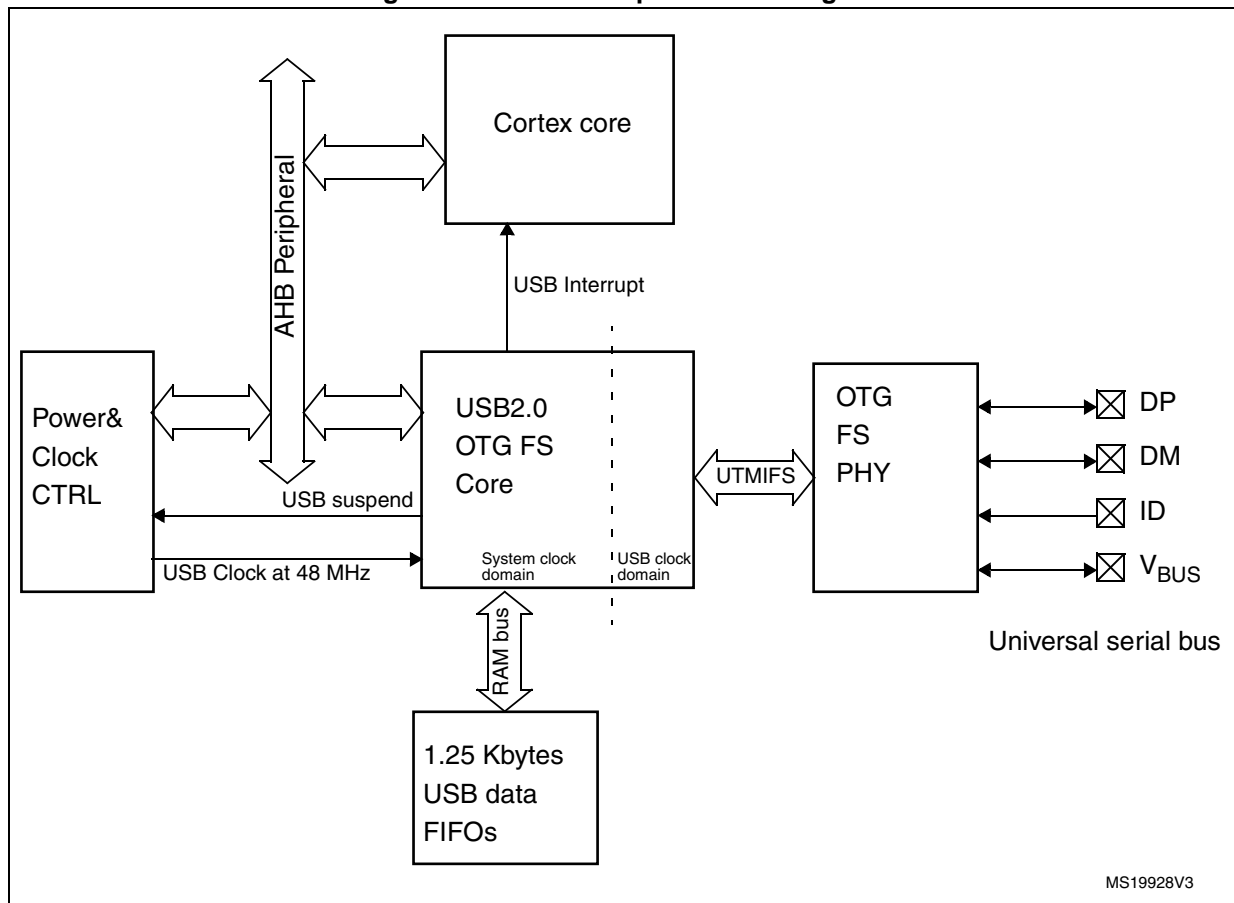
### 22.2.3 Peripheral-mode features

The OTG\_FS interface main features in peripheral-mode are the following:

- 1 bidirectional control endpoint0
- 3 IN endpoints (EPs) configurable to support Bulk, Interrupt or Isochronous transfers
- 3 OUT endpoints configurable to support Bulk, Interrupt or Isochronous transfers
- Management of a shared Rx FIFO and a Tx-OUT FIFO for efficient usage of the USB data RAM
- Management of up to 4 dedicated Tx-IN FIFOs (one for each active IN EP) to put less load on the application
- Support for the soft disconnect feature.

## 22.3 OTG\_FS functional description

Figure 242. OTG full-speed block diagram



MS19928V3

### 22.3.1 OTG full-speed core

The USB OTG FS receives the 48 MHz  $\pm 0.25\%$  clock from the reset and clock controller (RCC), via an external quartz. The USB clock is used for driving the 48 MHz domain at full-speed (12 Mbit/s) and must be enabled prior to configuring the OTG FS core.

The CPU reads and writes from/to the OTG FS core registers through the AHB peripheral bus. It is informed of USB events through the single USB OTG interrupt line described in [Section 22.15: OTG\\_FS interrupts](#).

The CPU submits data over the USB by writing 32-bit words to dedicated OTG\_FS locations (push registers). The data are then automatically stored into Tx-data FIFOs configured within the USB data RAM. There is one Tx-FIFO push register for each in-endpoint (peripheral mode) or out-channel (host mode).

The CPU receives the data from the USB by reading 32-bit words from dedicated OTG\_FS addresses (pop registers). The data are then automatically retrieved from a shared Rx-FIFO configured within the 1.25 KB USB data RAM. There is one Rx-FIFO pop register for each out-endpoint or in-channel.

The USB protocol layer is driven by the serial interface engine (SIE) and serialized over the USB by the full-/low-speed transceiver module within the on-chip physical layer (PHY).

### 22.3.2 Full-speed OTG PHY

The embedded full-speed OTG PHY is controlled by the OTG FS core and conveys USB control & data signals through the full-speed subset of the UTMI+ Bus (UTMIFS). It provides the physical support to USB connectivity.

The full-speed OTG PHY includes the following components:

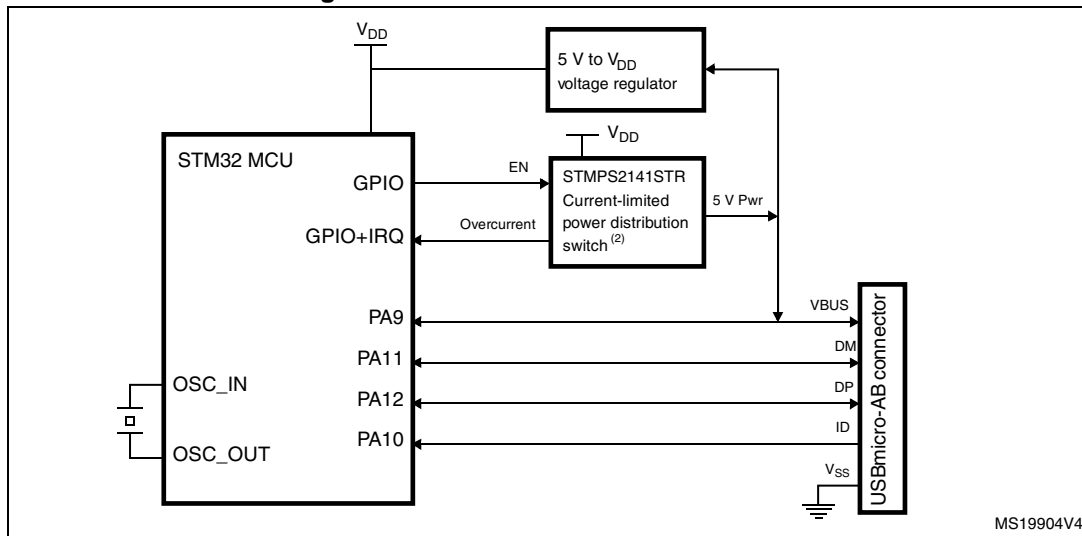
- FS/LS transceiver module used by both host and device. It directly drives transmission and reception on the single-ended USB lines.
- integrated ID pull-up resistor used to sample the ID line for A/B device identification.
- DP/DM integrated pull-up and pull-down resistors controlled by the OTG\_FS core depending on the current role of the device. As a peripheral, it enables the DP pull-up resistor to signal full-speed peripheral connections as soon as  $V_{BUS}$  is sensed to be at a valid level (B-session valid). In host mode, pull-down resistors are enabled on both DP/DM. Pull-up and pull-down resistors are dynamically switched when the device's role is changed via the host negotiation protocol (HNP).
- Pull-up/pull-down resistor ECN circuit. The DP pull-up consists of 2 resistors controlled separately from the OTG\_FS as per the resistor Engineering Change Notice applied to USB Rev2.0. The dynamic trimming of the DP pull-up strength allows for better noise rejection and Tx/Rx signal quality.
- $V_{BUS}$  sensing comparators with hysteresis used to detect  $V_{BUS}$  Valid, A-B Session Valid and session-end voltage thresholds. They are used to drive the session request protocol (SRP), detect valid startup and end-of-session conditions, and constantly monitor the  $V_{BUS}$  supply during USB operations.
- $V_{BUS}$  pulsing method circuit used to charge/discharge  $V_{BUS}$  through resistors during the SRP (weak drive).

**Caution:** To guarantee a correct operation for the USB OTG FS peripheral, the AHB frequency should be higher than 14.2 MHz.



## 22.4 OTG dual role device (DRD)

Figure 243. OTG A-B device connection



1. External voltage regulator only needed when building a V<sub>BUS</sub> powered device
2. STMP2141STR needed only if the application has to support a V<sub>BUS</sub> powered device. A basic power switch can be used if 5 V are available on the application board.

### 22.4.1 ID line detection

The host or peripheral (the default) role is assumed depending on the ID input pin. The ID line status is determined on plugging in the USB, depending on which side of the USB cable is connected to the micro-AB receptacle.

- If the B-side of the USB cable is connected with a floating ID wire, the integrated pull-up resistor detects a high ID level and the default Peripheral role is confirmed. In this configuration the OTG\_FS complies with the standard FSM described by section 6.8.2: On-The-Go B-device of the On-The-Go Specification Rev1.3 supplement to the USB2.0.
- If the A-side of the USB cable is connected with a grounded ID, the OTG\_FS issues an ID line status change interrupt (CIDSCHG bit in OTG\_FS\_GINTSTS) for host software initialization, and automatically switches to the host role. In this configuration the OTG\_FS complies with the standard FSM described by section 6.8.1: On-The-Go A-device of the On-The-Go Specification Rev1.3 supplement to the USB2.0.

### 22.4.2 HNP dual role device

The HNP capable bit in the Global USB configuration register (HNPCAP bit in OTG\_FS\_GUSBCFG) enables the OTG\_FS core to dynamically change its role from A-host to A-peripheral and vice-versa, or from B-Peripheral to B-host and vice-versa according to the host negotiation protocol (HNP). The current device status can be read by the combined values of the Connector ID Status bit in the Global OTG control and status register (CIDSTS bit in OTG\_FS\_GOTGCTL) and the current mode of operation bit in the global interrupt and status register (CMOD bit in OTG\_FS\_GINTSTS).

The HNP program model is described in detail in [Section 22.17: OTG\\_FS programming model](#).

### 22.4.3 SRP dual role device

The SRP capable bit in the global USB configuration register (SRPCAP bit in OTG\_FS\_GUSBCFG) enables the OTG\_FS core to switch off the generation of  $V_{BUS}$  for the A-device to save power. Note that the A-device is always in charge of driving  $V_{BUS}$  regardless of the host or peripheral role of the OTG\_FS.

the SRP A/B-device program model is described in detail in [Section 22.17: OTG\\_FS programming model](#).

## 22.5 USB peripheral

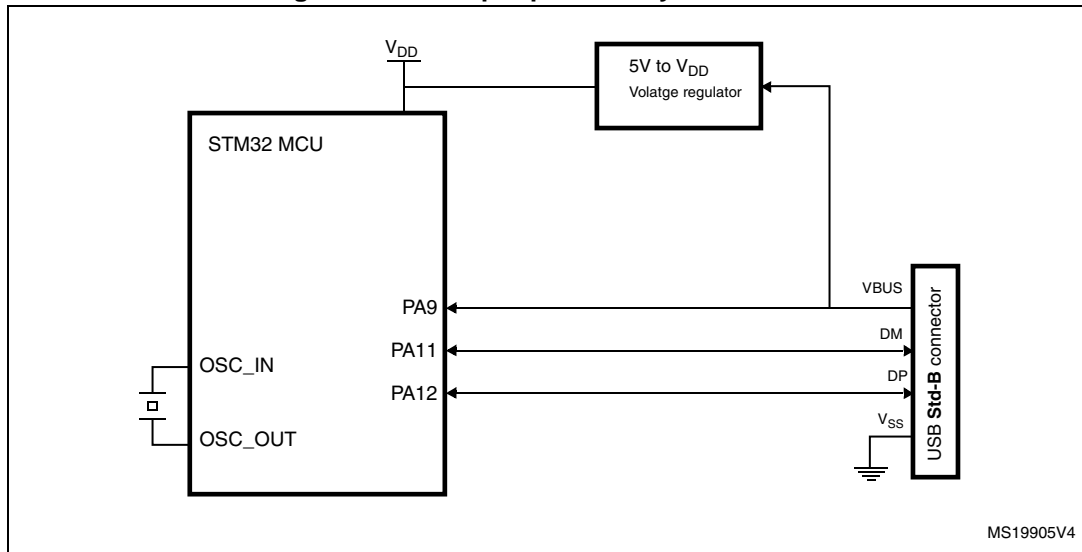
This section gives the functional description of the OTG\_FS in the USB peripheral mode. The OTG\_FS works as an USB peripheral in the following circumstances:

- OTG B-Peripheral
  - OTG B-device default state if B-side of USB cable is plugged in
- OTG A-Peripheral
  - OTG A-device state after the HNP switches the OTG\_FS to its peripheral role
- B-device
  - If the ID line is present, functional and connected to the B-side of the USB cable, and the HNP-capable bit in the Global USB Configuration register (HNPCAP bit in OTG\_FS\_GUSBCFG) is cleared (see On-The-Go Rev1.3 par. 6.8.3).
- Peripheral only (see [Figure 244: USB peripheral-only connection](#))
  - The force device mode bit in the Global USB configuration register (FDMOD in OTG\_FS\_GUSBCFG) is set to 1, forcing the OTG\_FS core to work as a USB peripheral-only (see On-The-Go Rev1.3 par. 6.8.3). In this case, the ID line is ignored even if present on the USB connector.

*Note:* To build a bus-powered device implementation in case of the B-device or peripheral-only configuration, an external regulator has to be added that generates the  $V_{DD}$  chip-supply from  $V_{BUS}$ .

The  $V_{BUS}$  pin can be freed by disabling the  $V_{BUS}$  sensing option. This is done by setting the NOVBUSSENS bit in the OTG\_FS\_GCCFG register. In this case the  $V_{BUS}$  is considered internally to be always at  $V_{BUS}$  valid level (5 V).

Figure 244. USB peripheral-only connection



1. Use a regulator to build a bus-powered device.

### 22.5.1 SRP-capable peripheral

The SRP capable bit in the Global USB configuration register (SRPCAP bit in OTG\_FS\_GUSBCFG) enables the OTG\_FS to support the session request protocol (SRP). In this way, it allows the remote A-device to save power by switching off  $V_{BUS}$  while the USB session is suspended.

The SRP peripheral mode program model is described in detail in the [B-device session request protocol](#) section.

### 22.5.2 Peripheral states

#### Powered state

The  $V_{BUS}$  input detects the B-Session valid voltage by which the USB peripheral is allowed to enter the powered state (see USB2.0 par9.1). The OTG\_FS then automatically connects the DP pull-up resistor to signal full-speed device connection to the host and generates the session request interrupt (SRQINT bit in OTG\_FS\_GINTSTS) to notify the powered state.

The  $V_{BUS}$  input also ensures that valid  $V_{BUS}$  levels are supplied by the host during USB operations. If a drop in  $V_{BUS}$  below B-session valid happens to be detected (for instance because of a power disturbance or if the host port has been switched off), the OTG\_FS automatically disconnects and the session end detected (SEDET bit in OTG\_FS\_GOTGINT) interrupt is generated to notify that the OTG\_FS has exited the powered state.

In the powered state, the OTG\_FS expects to receive some reset signaling from the host. No other USB operation is possible. When a reset signaling is received the reset detected interrupt (USBRST in OTG\_FS\_GINTSTS) is generated. When the reset signaling is complete, the enumeration done interrupt (ENUMDNE bit in OTG\_FS\_GINTSTS) is generated and the OTG\_FS enters the Default state.

### Soft disconnect

The powered state can be exited by software with the soft disconnect feature. The DP pull-up resistor is removed by setting the soft disconnect bit in the device control register (SDIS bit in OTG\_FS\_DCTL), causing a device disconnect detection interrupt on the host side even though the USB cable was not really removed from the host port.

### Default state

In the Default state the OTG\_FS expects to receive a SET\_ADDRESS command from the host. No other USB operation is possible. When a valid SET\_ADDRESS command is decoded on the USB, the application writes the corresponding number into the device address field in the device configuration register (DAD bit in OTG\_FS\_DCFG). The OTG\_FS then enters the address state and is ready to answer host transactions at the configured USB address.

### Suspended state

The OTG\_FS peripheral constantly monitors the USB activity. After counting 3 ms of USB idleness, the early suspend interrupt (ESUSP bit in OTG\_FS\_GINTSTS) is issued, and confirmed 3 ms later, if appropriate, by the suspend interrupt (USBSUSP bit in OTG\_FS\_GINTSTS). The device suspend bit is then automatically set in the device status register (SUSPSTS bit in OTG\_FS\_DSTS) and the OTG\_FS enters the suspended state.

The suspended state may optionally be exited by the device itself. In this case the application sets the remote wakeup signaling bit in the device control register (RWUSIG bit in OTG\_FS\_DCTL) and clears it after 1 to 15 ms.

When a resume signaling is detected from the host, the resume interrupt (WKUPINT bit in OTG\_FS\_GINTSTS) is generated and the device suspend bit is automatically cleared.

## 22.5.3 Peripheral endpoints

The OTG\_FS core instantiates the following USB endpoints:

- Control endpoint 0:
  - Bidirectional and handles control messages only
  - Separate set of registers to handle in and out transactions
  - Proper control (OTG\_FS\_DIEPCTL0/OTG\_FS\_DOEPCTL0), transfer configuration (OTG\_FS\_DIEPTSIZ0/OTG\_FS\_DIEPTSIZ0), and status-interrupt (OTG\_FS\_DIEPINTx)/OTG\_FS\_DOEPINT0 registers. The available set of bits inside the control and transfer size registers slightly differs from that of other endpoints
- 3 IN endpoints
  - Each of them can be configured to support the isochronous, bulk or interrupt transfer type
  - Each of them has proper control (OTG\_FS\_DIEPCTLx), transfer configuration (OTG\_FS\_DIEPTSIZx), and status-interrupt (OTG\_FS\_DIEPINTx) registers
  - The Device IN endpoints common interrupt mask register (OTG\_FS\_DIEPMSK) is available to enable/disable a single kind of endpoint interrupt source on all of the IN endpoints (EPO included)
  - Support for incomplete isochronous IN transfer interrupt (IISOIXFR bit in OTG\_FS\_GINTSTS), asserted when there is at least one isochronous IN endpoint

on which the transfer is not completed in the current frame. This interrupt is asserted along with the end of periodic frame interrupt (OTG\_FS\_GINTSTS/EOPF).

- 3 OUT endpoints
  - Each of them can be configured to support the isochronous, bulk or interrupt transfer type
  - Each of them has a proper control (OTG\_FS\_DOEPCTLx), transfer configuration (OTG\_FS\_DOEPTSIZx) and status-interrupt (OTG\_FS\_DOEPINTx) register
  - Device Out endpoints common interrupt mask register (OTG\_FS\_DOEPMSK) is available to enable/disable a single kind of endpoint interrupt source on all of the OUT endpoints (EP0 included)
  - Support for incomplete isochronous OUT transfer interrupt (INCOMPISOOUT bit in OTG\_FS\_GINTSTS), asserted when there is at least one isochronous OUT endpoint on which the transfer is not completed in the current frame. This interrupt is asserted along with the end of periodic frame interrupt (OTG\_FS\_GINTSTS/EOPF).

### Endpoint control

- The following endpoint controls are available to the application through the device endpoint-x IN/OUT control register (DIEPCTLx/DOEPCTLx):
  - Endpoint enable/disable
  - Endpoint activate in current configuration
  - Program USB transfer type (isochronous, bulk, interrupt)
  - Program supported packet size
  - Program Tx-FIFO number associated with the IN endpoint
  - Program the expected or transmitted data0/data1 PID (bulk/interrupt only)
  - Program the even/odd frame during which the transaction is received or transmitted (isochronous only)
  - Optionally program the NAK bit to always negative-acknowledge the host regardless of the FIFO status
  - Optionally program the STALL bit to always stall host tokens to that endpoint
  - Optionally program the SNOOP mode for OUT endpoint not to check the CRC field of received data

### Endpoint transfer

The device endpoint-x transfer size registers (DIEPTSIZx/DOEPTSIZx) allow the application to program the transfer size parameters and read the transfer status. Programming must be done before setting the endpoint enable bit in the endpoint control register. Once the endpoint is enabled, these fields are read-only as the OTG FS core updates them with the current transfer status.

The following transfer parameters can be programmed:

- Transfer size in bytes
- Number of packets that constitute the overall transfer size

## Endpoint status/interrupt

The device endpoint-x interrupt registers (DIEPINT<sub>x</sub>/DOPEPINT<sub>x</sub>) indicate the status of an endpoint with respect to USB- and AHB-related events. The application must read these registers when the OUT endpoint interrupt bit or the IN endpoint interrupt bit in the core interrupt register (OEPINT bit in OTG\_FS\_GINTSTS or IEPINT bit in OTG\_FS\_GINTSTS, respectively) is set. Before the application can read these registers, it must first read the device all endpoints interrupt (OTG\_FS\_DAIN<sub>T</sub>) register to get the exact endpoint number for the device endpoint-x interrupt register. The application must clear the appropriate bit in this register to clear the corresponding bits in the DAIN<sub>T</sub> and GINTSTS registers

The peripheral core provides the following status checks and interrupt generation:

- Transfer completed interrupt, indicating that data transfer was completed on both the application (AHB) and USB sides
- Setup stage has been done (control-out only)
- Associated transmit FIFO is half or completely empty (in endpoints)
- NAK acknowledge has been transmitted to the host (isochronous-in only)
- IN token received when Tx-FIFO was empty (bulk-in/interrupt-in only)
- Out token received when endpoint was not yet enabled
- Babble error condition has been detected
- Endpoint disable by application is effective
- Endpoint NAK by application is effective (isochronous-in only)
- More than 3 back-to-back setup packets were received (control-out only)
- Timeout condition detected (control-in only)
- Isochronous out packet has been dropped, without generating an interrupt

## 22.6 USB host

This section gives the functional description of the OTG\_FS in the USB host mode. The OTG\_FS works as a USB host in the following circumstances:

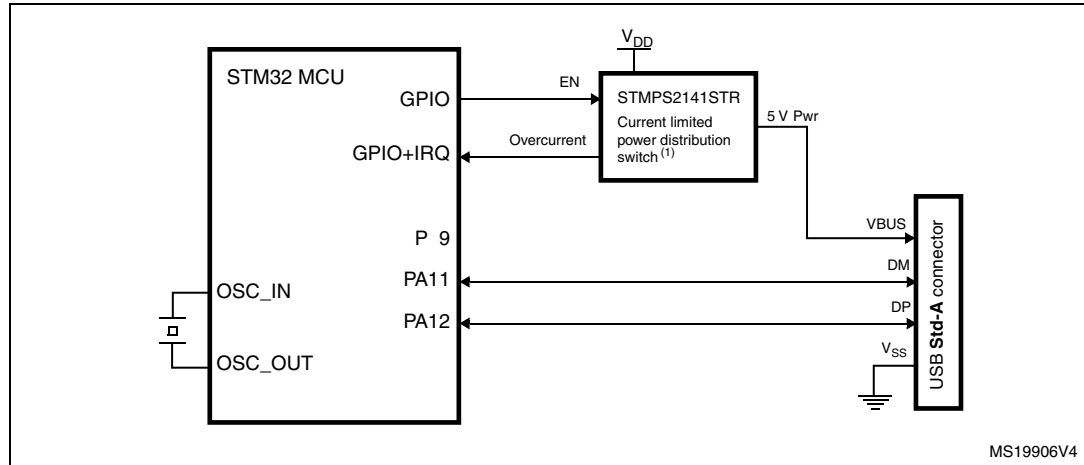
- OTG A-host
  - OTG A-device default state when the A-side of the USB cable is plugged in
- OTG B-host
  - OTG B-device after HNP switching to the host role
- A-device
  - If the ID line is present, functional and connected to the A-side of the USB cable, and the HNP-capable bit is cleared in the Global USB Configuration register (HNPCAP bit in OTG\_FS\_GUSBCFG). Integrated pull-down resistors are automatically set on the DP/DM lines.
- Host only (see figure [Figure 245: USB host-only connection](#)).
  - The force host mode bit in the global USB configuration register (FHMOD bit in OTG\_FS\_GUSBCFG) forces the OTG\_FS core to work as a USB host-only. In this case, the ID line is ignored even if present on the USB connector. Integrated pull-down resistors are automatically set on the DP/DM lines.

*Note:* On-chip 5 V  $V_{BUS}$  generation is not supported. For this reason, a charge pump or, if 5 V are available on the application board, a basic power switch must be added externally to drive

the 5 V  $V_{BUS}$  line. The external charge pump can be driven by any GPIO output. This is required for the OTG A-host, A-device and host-only configurations.

The  $V_{BUS}$  input ensures that valid  $V_{BUS}$  levels are supplied by the charge pump during USB operations while the charge pump overcurrent output can be input to any GPIO pin configured to generate port interrupts. The overcurrent ISR must promptly disable the  $V_{BUS}$  generation.

Figure 245. USB host-only connection



1. STMPS2141STR needed only if the application has to support a  $V_{BUS}$  powered device. A basic power switch can be used if 5 V are available on the application board.
2.  $V_{DD}$  range is between 2 V and 3.6 V.

### 22.6.1 SRP-capable host

SRP support is available through the SRP capable bit in the global USB configuration register (SRPCAP bit in OTG\_FS\_GUSBCFG). With the SRP feature enabled, the host can save power by switching off the  $V_{BUS}$  power while the USB session is suspended.

The SRP host mode program model is described in detail in the [A-device session request protocol](#) section.

### 22.6.2 USB host states

#### Host port power

On-chip 5 V  $V_{BUS}$  generation is not supported. For this reason, a charge pump or, if 5 V are available on the application board, a basic power switch, must be added externally to drive the 5 V  $V_{BUS}$  line. The external charge pump can be driven by any GPIO output. When the application decides to power on  $V_{BUS}$  using the chosen GPIO, it must also set the port power bit in the host port control and status register (PPWR bit in OTG\_FS\_HPRT).

#### $V_{BUS}$ valid

When HNP or SRP is enabled the VBUS sensing pin (PA9) pin should be connected to  $V_{BUS}$ . The  $V_{BUS}$  input ensures that valid  $V_{BUS}$  levels are supplied by the charge pump during USB operations. Any unforeseen  $V_{BUS}$  voltage drop below the  $V_{BUS}$  valid threshold (4.25 V) leads to an OTG interrupt triggered by the session end detected bit (SEDET bit in OTG\_FS\_GOTGINT). The application is then required to remove the  $V_{BUS}$  power and clear the port power bit.

When HNP and SRP are both disabled, the VBUS sensing pin (PA9) should not be connected to  $V_{BUS}$ . This pin can be used as GPIO.

The charge pump overcurrent flag can also be used to prevent electrical damage. Connect the overcurrent flag output from the charge pump to any GPIO input and configure it to generate a port interrupt on the active level. The overcurrent ISR must promptly disable the  $V_{BUS}$  generation and clear the port power bit.

### Host detection of a peripheral connection

If SRP or HNP are enabled, even if USB peripherals or B-devices can be attached at any time, the OTG\_FS will not detect any bus connection. When  $V_{BUS}$  is at a valid level and a remote B-device is attached, the OTG\_FS core issues a host port interrupt triggered by the device connected bit in the host port control and status register (PCDET bit in OTG\_FS\_HPRT).

When HNP and SRP are both disabled, USB peripherals or B-device are detected as soon as they are connected. The OTG\_FS core issues a host port interrupt triggered by the device connected bit in the host port control and status (PCDET bit in OTG\_FS\_HPRT).

### Host detection of peripheral a disconnection

The peripheral disconnection event triggers the disconnect detected interrupt (DISCINT bit in OTG\_FS\_GINTSTS).

### Host enumeration

After detecting a peripheral connection the host must start the enumeration process by sending USB reset and configuration commands to the new peripheral.

Before starting to drive a USB reset, the application waits for the OTG interrupt triggered by the debounce done bit (DBCDNE bit in OTG\_FS\_GOTGINT), which indicates that the bus is stable again after the electrical debounce caused by the attachment of a pull-up resistor on DP (FS) or DM (LS).

The application drives a USB reset signaling (single-ended zero) over the USB by keeping the port reset bit set in the host port control and status register (PRST bit in OTG\_FS\_HPRT) for a minimum of 10 ms and a maximum of 20 ms. The application takes care of the timing count and then of clearing the port reset bit.

Once the USB reset sequence has completed, the host port interrupt is triggered by the port enable/disable change bit (PENCHNG bit in OTG\_FS\_HPRT). This informs the application that the speed of the enumerated peripheral can be read from the port speed field in the host port control and status register (PSPD bit in OTG\_FS\_HPRT) and that the host is starting to drive SOFs (FS) or Keep alives (LS). The host is now ready to complete the peripheral enumeration by sending peripheral configuration commands.

### Host suspend

The application decides to suspend the USB activity by setting the port suspend bit in the host port control and status register (PSUSP bit in OTG\_FS\_HPRT). The OTG\_FS core stops sending SOFs and enters the suspended state.

The suspended state can be optionally exited on the remote device's initiative (remote wakeup). In this case the remote wakeup interrupt (WKUPINT bit in OTG\_FS\_GINTSTS) is generated upon detection of a remote wakeup signaling, the port resume bit in the host port control and status register (PRES bit in OTG\_FS\_HPRT) self-sets, and resume signaling is



automatically driven over the USB. The application must time the resume window and then clear the port resume bit to exit the suspended state and restart the SOF.

If the suspended state is exited on the host initiative, the application must set the port resume bit to start resume signaling on the host port, time the resume window and finally clear the port resume bit.

### 22.6.3 Host channels

The OTG\_FS core instantiates 8 host channels. Each host channel supports an USB host transfer (USB pipe). The host is not able to support more than 8 transfer requests at the same time. If more than 8 transfer requests are pending from the application, the host controller driver (HCD) must re-allocate channels when they become available from previous duty, that is, after receiving the transfer completed and channel halted interrupts.

Each host channel can be configured to support in/out and any type of periodic/nonperiodic transaction. Each host channel makes use of proper control (HCCHAR $x$ ), transfer configuration (HCTSIZ $x$ ) and status/interrupt (HCINT $x$ ) registers with associated mask (HCINTMSK $x$ ) registers.

#### Host channel control

- The following host channel controls are available to the application through the host channel- $x$  characteristics register (HCCHAR $x$ ):
  - Channel enable/disable
  - Program the FS/LS speed of target USB peripheral
  - Program the address of target USB peripheral
  - Program the endpoint number of target USB peripheral
  - Program the transfer IN/OUT direction
  - Program the USB transfer type (control, bulk, interrupt, isochronous)
  - Program the maximum packet size (MPS)
  - Program the periodic transfer to be executed during odd/even frames

#### Host channel transfer

The host channel transfer size registers (HCTSIZ $x$ ) allow the application to program the transfer size parameters, and read the transfer status. Programming must be done before setting the channel enable bit in the host channel characteristics register. Once the endpoint is enabled the packet count field is read-only as the OTG FS core updates it according to the current transfer status.

- The following transfer parameters can be programmed:
  - transfer size in bytes
  - number of packets making up the overall transfer size
  - initial data PID

#### Host channel status/interrupt

The host channel- $x$  interrupt register (HCINT $x$ ) indicates the status of an endpoint with respect to USB- and AHB-related events. The application must read these registers when the host channels interrupt bit in the core interrupt register (HCINT bit in OTG\_FS\_GINTSTS) is set. Before the application can read these registers, it must first read the host all channels interrupt (HCAINT) register to get the exact channel number for the host channel- $x$  interrupt

register. The application must clear the appropriate bit in this register to clear the corresponding bits in the HAIN and GINTSTS registers. The mask bits for each interrupt source of each channel are also available in the OTG\_FS\_HCINTMSK-x register.

- The host core provides the following status checks and interrupt generation:
  - Transfer completed interrupt, indicating that the data transfer is complete on both the application (AHB) and USB sides
  - Channel has stopped due to transfer completed, USB transaction error or disable command from the application
  - Associated transmit FIFO is half or completely empty (IN endpoints)
  - ACK response received
  - NAK response received
  - STALL response received
  - USB transaction error due to CRC failure, timeout, bit stuff error, false EOP
  - Babble error
  - fraMe overrun
  - dAta toggle error

#### 22.6.4 Host scheduler

The host core features a built-in hardware scheduler which is able to autonomously re-order and manage the USB transaction requests posted by the application. At the beginning of each frame the host executes the periodic (isochronous and interrupt) transactions first, followed by the nonperiodic (control and bulk) transactions to achieve the higher level of priority granted to the isochronous and interrupt transfer types by the USB specification.

The host processes the USB transactions through request queues (one for periodic and one for nonperiodic). Each request queue can hold up to 8 entries. Each entry represents a pending transaction request from the application, and holds the IN or OUT channel number along with other information to perform a transaction on the USB. The order in which the requests are written to the queue determines the sequence of the transactions on the USB interface.

At the beginning of each frame, the host processes the periodic request queue first, followed by the nonperiodic request queue. The host issues an incomplete periodic transfer interrupt (IPXFR bit in OTG\_FS\_GINTSTS) if an isochronous or interrupt transaction scheduled for the current frame is still pending at the end of the current frame. The OTG HS core is fully responsible for the management of the periodic and nonperiodic request queues. The periodic transmit FIFO and queue status register (HPTXSTS) and nonperiodic transmit FIFO and queue status register (HNPTXSTS) are read-only registers which can be used by the application to read the status of each request queue. They contain:

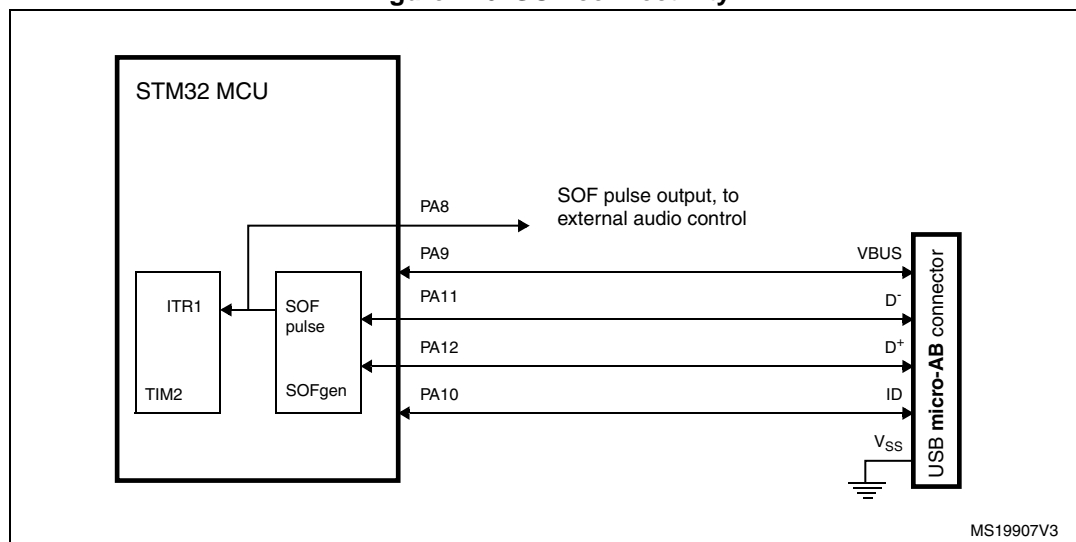
- The number of free entries currently available in the periodic (nonperiodic) request queue (8 max)
- Free space currently available in the periodic (nonperiodic) Tx-FIFO (out-transactions)
- IN/OUT token, host channel number and other status information.

As request queues can hold a maximum of 8 entries each, the application can push to schedule host transactions in advance with respect to the moment they physically reach the SB for a maximum of 8 pending periodic transactions plus 8 pending nonperiodic transactions.

To post a transaction request to the host scheduler (queue) the application must check that there is at least 1 entry available in the periodic (nonperiodic) request queue by reading the PTXQSAV bits in the OTG\_FS\_HNPTXSTS register or NPTQSAV bits in the OTG\_FS\_HNPTXSTS register.

## 22.7 SOF trigger

Figure 246. SOF connectivity



The OTG FS core provides means to monitor, track and configure SOF framing in the host and peripheral, as well as an SOF pulse output connectivity feature.

Such utilities are especially useful for adaptive audio clock generation techniques, where the audio peripheral needs to synchronize to the isochronous stream provided by the PC, or the host needs to trim its framing rate according to the requirements of the audio peripheral.

### 22.7.1 Host SOFs

In host mode the number of PHY clocks occurring between the generation of two consecutive SOF (FS) or Keep-alive (LS) tokens is programmable in the host frame interval register (HFIR), thus providing application control over the SOF framing period. An interrupt is generated at any start of frame (SOF bit in OTH\_FS\_GINTSTS). The current frame number and the time remaining until the next SOF are tracked in the host frame number register (HFNUM).

An SOF pulse signal, generated at any SOF starting token and with a width of 12 system clock cycles, can be made available externally on the SOF pin using the SOFOUTEN bit in the global control and configuration register. The SOF pulse is also internally connected to the input trigger of timer 2 (TIM2), so that the input capture feature, the output compare feature and the timer can be triggered by the SOF pulse. The TIM2 connection is enabled register.

### 22.7.2 Peripheral SOFs

In device mode, the start of frame interrupt is generated each time an SOF token is received on the USB (SOF bit in OTH\_FS\_GINTSTS). The corresponding frame number can be read

from the device status register (FNSOF bit in OTG\_FS\_DSTS). An SOF pulse signal with a width of 12 system clock cycles is also generated and can be made available externally on the SOF pin by using the SOF output enable bit in the global control and configuration register (SOFOUTEN bit in OTG\_FS\_GCCFG). The SOF pulse signal is also internally connected to the TIM2 input trigger, so that the input capture feature, the output compare feature and the timer can be triggered by the SOF pulse. The TIM2 connection is enabled .

The end of periodic frame interrupt (GINTSTS/EOPF) is used to notify the application when 80%, 85%, 90% or 95% of the time frame interval elapsed depending on the periodic frame interval field in the device configuration register (PFIVL bit in OTG\_FS\_DCFG). This feature can be used to determine if all of the isochronous traffic for that frame is complete.

## 22.8 Power options

The power consumption of the OTG PHY is controlled by three bits in the general core configuration register:

- PHY power down (GCCFG/PWRDWN)  
It switches on/off the full-speed transceiver module of the PHY. It must be preliminarily set to allow any USB operation.
- A- $V_{BUS}$  sensing enable (GCCFG/VBUSASEN)  
It switches on/off the  $V_{BUS}$  comparators associated with A-device operations. It must be set when in A-device (USB host) mode and during HNP.
- B- $V_{BUS}$  sensing enable (GCCFG/VBUSASEN)  
It switches on/off the  $V_{BUS}$  comparators associated with B-device operations. It must be set when in B-device (USB peripheral) mode and during HNP.

Power reduction techniques are available while in the USB suspended state, when the USB session is not yet valid or the device is disconnected.

- Stop PHY clock (STPPCLK bit in OTG\_FS\_PCGCCTL)  
When setting the stop PHY clock bit in the clock gating control register, most of the 48 MHz clock domain internal to the OTG full-speed core is switched off by clock gating. The dynamic power consumption due to the USB clock switching activity is cut even if the 48 MHz clock input is kept running by the application  
Most of the transceiver is also disabled, and only the part in charge of detecting the asynchronous resume or remote wakeup event is kept alive.
- Gate HCLK (GATEHCLK bit in OTG\_FS\_PCGCCTL)  
When setting the Gate HCLK bit in the clock gating control register, most of the system clock domain internal to the OTG\_FS core is switched off by clock gating. Only the register read and write interface is kept alive. The dynamic power consumption due to the USB clock switching activity is cut even if the system clock is kept running by the application for other purposes.
- USB system stop  
When the OTG\_FS is in the USB suspended state, the application may decide to drastically reduce the overall power consumption by a complete shut down of all the clock sources in the system. USB System Stop is activated by first setting the Stop

PHY clock bit and then configuring the system deep sleep mode in the power control system module (PWR).

The OTG\_FS core automatically reactivates both system and USB clocks by asynchronous detection of remote wakeup (as an host) or resume (as a device) signaling on the USB.

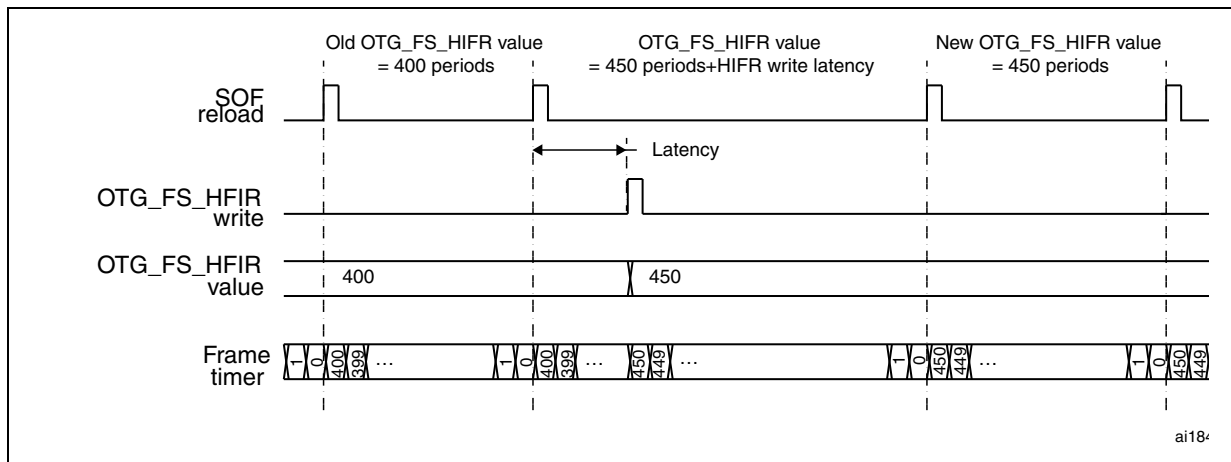
To save dynamic power, the USB data FIFO is clocked only when accessed by the OTG\_FS core.

## 22.9 Dynamic update of the OTG\_FS\_HFIR register

The USB core embeds a dynamic trimming capability of micro-SOF framing period in host mode allowing to synchronize an external device with the micro-SOF frames.

When the OTG\_HS\_HFIR register is changed within a current micro-SOF frame, the SOF period correction is applied in the next frame as described in [Figure 247](#).

Figure 247. Updating OTG\_FS\_HFIR dynamically

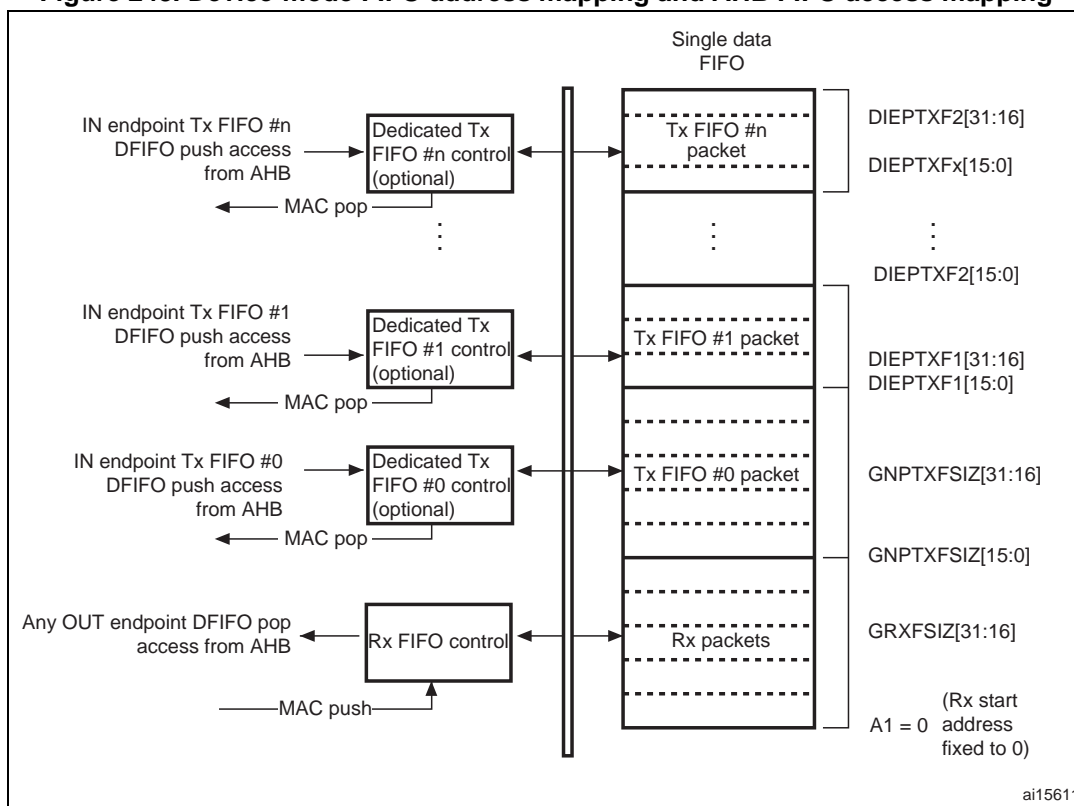


## 22.10 USB data FIFOs

The USB system features 1.25 Kbyte of dedicated RAM with a sophisticated FIFO control mechanism. The packet FIFO controller module in the OTG\_FS core organizes RAM space into Tx-FIFOs into which the application pushes the data to be temporarily stored before the USB transmission, and into a single Rx FIFO where the data received from the USB are temporarily stored before retrieval (popped) by the application. The number of instructed FIFOs and how these are organized inside the RAM depends on the device's role. In peripheral mode an additional Tx-FIFO is instructed for each active IN endpoint. Any FIFO size is software configured to better meet the application requirements.

## 22.11 Peripheral FIFO architecture

Figure 248. Device-mode FIFO address mapping and AHB FIFO access mapping



### 22.11.1 Peripheral Rx FIFO

The OTG peripheral uses a single receive FIFO that receives the data directed to all OUT endpoints. Received packets are stacked back-to-back until free space is available in the Rx-FIFO. The status of the received packet (which contains the OUT endpoint destination number, the byte count, the data PID and the validity of the received data) is also stored by the core on top of the data payload. When no more space is available, host transactions are NACKed and an interrupt is received on the addressed endpoint. The size of the receive FIFO is configured in the receive FIFO Size register (GRXFSIZ).

The single receive FIFO architecture makes it more efficient for the USB peripheral to fill in the receive RAM buffer:

- All OUT endpoints share the same RAM buffer (shared FIFO)
- The OTG FS core can fill in the receive FIFO up to the limit for any host sequence of OUT tokens

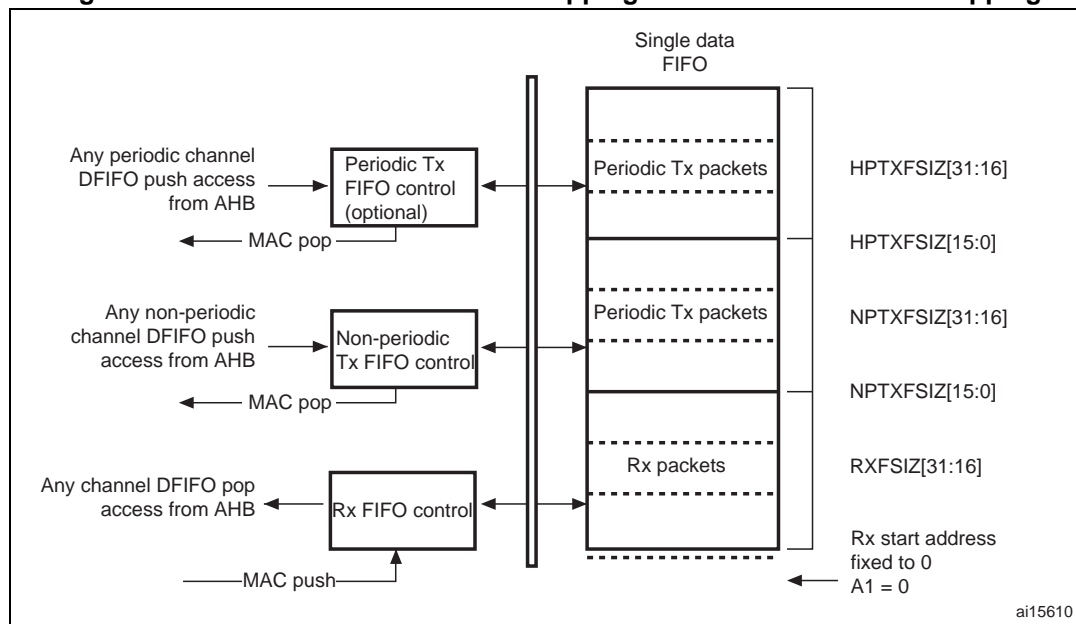
The application keeps receiving the Rx-FIFO non-empty interrupt (RXFLVL bit in OTG\_FS\_GINTSTS) as long as there is at least one packet available for download. It reads the packet information from the receive status read and pop register (GRXSTSP) and finally pops data off the receive FIFO by reading from the endpoint-related pop address.

### 22.11.2 Peripheral Tx FIFOs

The core has a dedicated FIFO for each IN endpoint. The application configures FIFO sizes by writing the non periodic transmit FIFO size register (OTG\_FS\_TX0FSIZ) for IN endpoint0 and the device IN endpoint transmit FIFOx registers (DIEPTXFx) for IN endpoint-x.

## 22.12 Host FIFO architecture

Figure 249. Host-mode FIFO address mapping and AHB FIFO access mapping



### 22.12.1 Host Rx FIFO

The host uses one receiver FIFO for all periodic and nonperiodic transactions. The FIFO is used as a receive buffer to hold the received data (payload of the received packet) from the USB until it is transferred to the system memory. Packets received from any remote IN endpoint are stacked back-to-back until free space is available. The status of each received packet with the host channel destination, byte count, data PID and validity of the received data are also stored into the FIFO. The size of the receive FIFO is configured in the receive FIFO size register (GRXFSIZ).

The single receive FIFO architecture makes it highly efficient for the USB host to fill in the receive data buffer:

- All IN configured host channels share the same RAM buffer (shared FIFO)
- The OTG FS core can fill in the receive FIFO up to the limit for any sequence of IN tokens driven by the host software

The application receives the Rx FIFO not-empty interrupt as long as there is at least one packet available for download. It reads the packet information from the receive status read and pop register and finally pops the data off the receive FIFO.

## 22.12.2 Host Tx FIFOs

The host uses one transmit FIFO for all non-periodic (control and bulk) OUT transactions and one transmit FIFO for all periodic (isochronous and interrupt) OUT transactions. FIFOs are used as transmit buffers to hold the data (payload of the transmit packet) to be transmitted over the USB. The size of the periodic (nonperiodic) Tx FIFO is configured in the host periodic (nonperiodic) transmit FIFO size (HPTXFSIZ/HNPTXFSIZ) register.

The two Tx FIFO implementation derives from the higher priority granted to the periodic type of traffic over the USB frame. At the beginning of each frame, the built-in host scheduler processes the periodic request queue first, followed by the nonperiodic request queue.

The two transmit FIFO architecture provides the USB host with separate optimization for periodic and nonperiodic transmit data buffer management:

- All host channels configured to support periodic (nonperiodic) transactions in the OUT direction share the same RAM buffer (shared FIFOs)
- The OTG FS core can fill in the periodic (nonperiodic) transmit FIFO up to the limit for any sequence of OUT tokens driven by the host software

The OTG\_FS core issues the periodic Tx FIFO empty interrupt (PTXFE bit in OTG\_FS\_GINTSTS) as long as the periodic Tx-FIFO is half or completely empty, depending on the value of the periodic Tx-FIFO empty level bit in the AHB configuration register (PTXFELVL bit in OTG\_FS\_GAHBCFG). The application can push the transmission data in advance as long as free space is available in both the periodic Tx FIFO and the periodic request queue. The host periodic transmit FIFO and queue status register (HPTXSTS) can be read to know how much space is available in both.

OTG\_FS core issues the non periodic Tx FIFO empty interrupt (NPTXFE bit in OTG\_FS\_GINTSTS) as long as the nonperiodic Tx FIFO is half or completely empty depending on the non periodic Tx FIFO empty level bit in the AHB configuration register (TXFELVL bit in OTG\_FS\_GAHBCFG). The application can push the transmission data as long as free space is available in both the nonperiodic Tx FIFO and nonperiodic request queue. The host nonperiodic transmit FIFO and queue status register (HNPTXSTS) can be read to know how much space is available in both.

## 22.13 FIFO RAM allocation

### 22.13.1 Device mode

**Receive FIFO RAM allocation:** the application should allocate RAM for SETUP Packets: 10 locations must be reserved in the receive FIFO to receive SETUP packets on control endpoint. The core does not use these locations, which are reserved for SETUP packets, to write any other data. One location is to be allocated for Global OUT NAK. Status information is written to the FIFO along with each received packet. Therefore, a minimum space of  $(\text{Largest Packet Size} / 4) + 1$  must be allocated to receive packets. If multiple isochronous endpoints are enabled, then at least two  $(\text{Largest Packet Size} / 4) + 1$  spaces must be allocated to receive back-to-back packets. Typically, two  $(\text{Largest Packet Size} / 4) + 1$  spaces are recommended so that when the previous packet is being transferred to the CPU, the USB can receive the subsequent packet.

Along with the last packet for each endpoint, transfer complete status information is also pushed to the FIFO. Typically, one location for each OUT endpoint is recommended.



**Transmit FIFO RAM allocation:** the minimum RAM space required for each IN Endpoint Transmit FIFO is the maximum packet size for that particular IN endpoint.

*Note:* More space allocated in the transmit IN Endpoint FIFO results in better performance on the USB.

## 22.13.2 Host mode

### Receive FIFO RAM allocation

Status information is written to the FIFO along with each received packet. Therefore, a minimum space of  $(\text{Largest Packet Size} / 4) + 1$  must be allocated to receive packets. If multiple isochronous channels are enabled, then at least two  $(\text{Largest Packet Size} / 4) + 1$  spaces must be allocated to receive back-to-back packets. Typically, two  $(\text{Largest Packet Size} / 4) + 1$  spaces are recommended so that when the previous packet is being transferred to the CPU, the USB can receive the subsequent packet.

Along with the last packet in the host channel, transfer complete status information is also pushed to the FIFO. So one location must be allocated for this.

### Transmit FIFO RAM allocation

The minimum amount of RAM required for the host Non-periodic Transmit FIFO is the largest maximum packet size among all supported non-periodic OUT channels.

Typically, two Largest Packet Sizes worth of space is recommended, so that when the current packet is under transfer to the USB, the CPU can get the next packet.

The minimum amount of RAM required for host periodic Transmit FIFO is the largest maximum packet size out of all the supported periodic OUT channels. If there is at least one Isochronous OUT endpoint, then the space must be at least two times the maximum packet size of that channel.

*Note:* More space allocated in the Transmit Non-periodic FIFO results in better performance on the USB.

## 22.14 USB system performance

Best USB and system performance is achieved owing to the large RAM buffers, the highly configurable FIFO sizes, the quick 32-bit FIFO access through AHB push/pop registers and, especially, the advanced FIFO control mechanism. Indeed, this mechanism allows the OTG\_FS to fill in the available RAM space at best regardless of the current USB sequence. With these features:

- The application gains good margins to calibrate its intervention in order to optimize the CPU bandwidth usage:
  - It can accumulate large amounts of transmission data in advance compared to when they are effectively sent over the USB
  - It benefits of a large time margin to download data from the single receive FIFO
- The USB Core is able to maintain its full operating rate, that is to provide maximum full-speed bandwidth with a great margin of autonomy versus application intervention:
  - It has a large reserve of transmission data at its disposal to autonomously manage the sending of data over the USB

- It has a lot of empty space available in the receive buffer to autonomously fill it in with the data coming from the USB

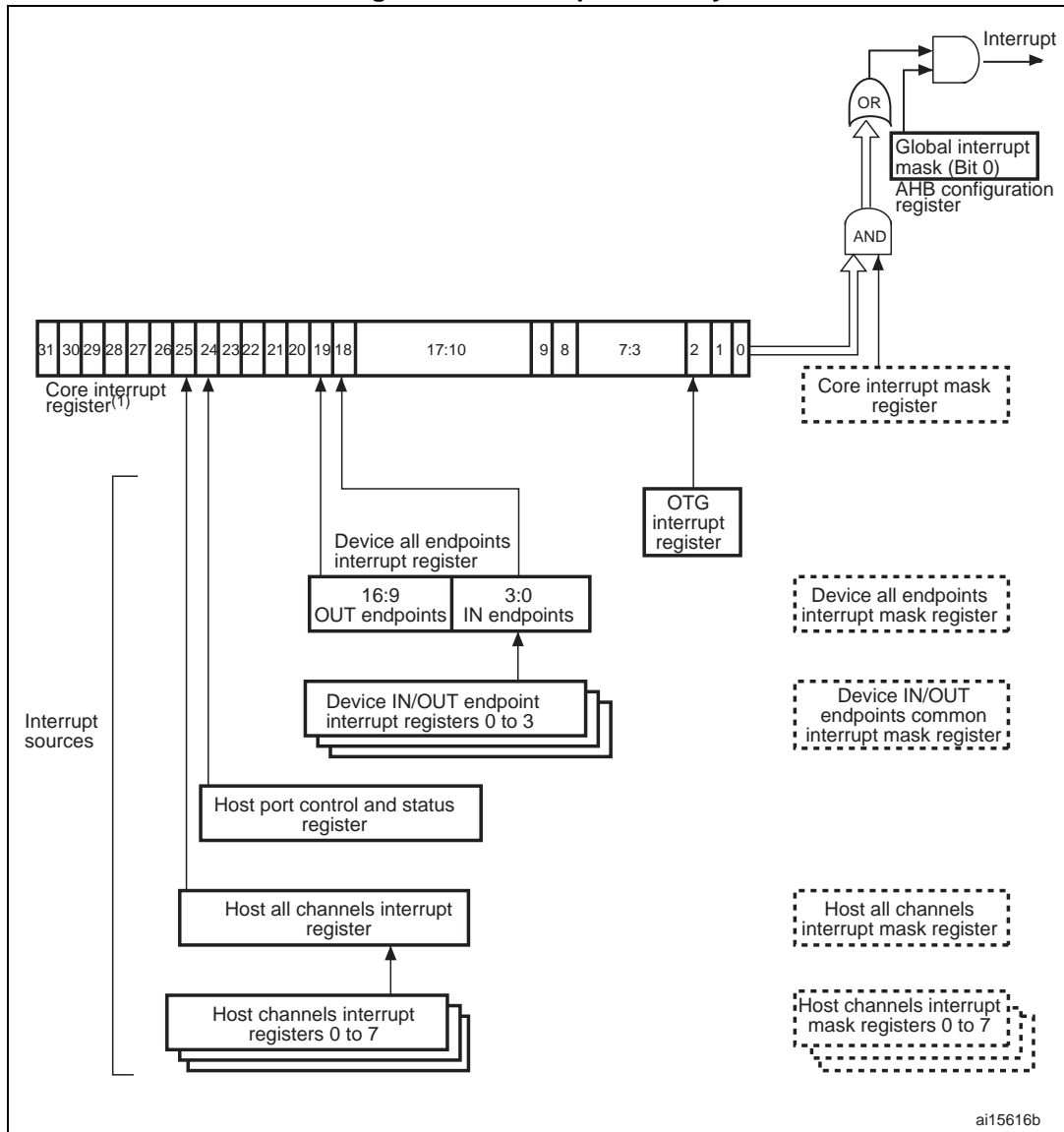
As the OTG\_FS core is able to fill in the 1.25 Kbyte RAM buffer very efficiently, and as 1.25 Kbyte of transmit/receive data is more than enough to cover a full speed frame, the USB system is able to withstand the maximum full-speed data rate for up to one USB frame (1 ms) without any CPU intervention.

## 22.15 OTG\_FS interrupts

When the OTG\_FS controller is operating in one mode, either device or host, the application must not access registers from the other mode. If an illegal access occurs, a mode mismatch interrupt is generated and reflected in the Core interrupt register (MMIS bit in the OTG\_FS\_GINTSTS register). When the core switches from one mode to the other, the registers in the new mode of operation must be reprogrammed as they would be after a power-on reset.

*Figure 250* shows the interrupt hierarchy.

Figure 250. Interrupt hierarchy



1. The core interrupt register bits are shown in [OTG\\_FS core interrupt register \(OTG\\_FS\\_GINTSTS\)](#) on [page 701](#).

## 22.16 OTG\_FS control and status registers

By reading from and writing to the control and status registers (CSRs) through the AHB slave interface, the application controls the OTG\_FS controller. These registers are 32 bits wide, and the addresses are 32-bit block aligned. The OTG\_FS registers must be accessed by words (32 bits).

CSRs are classified as follows:

- Core global registers
- Host-mode registers
- Host global registers

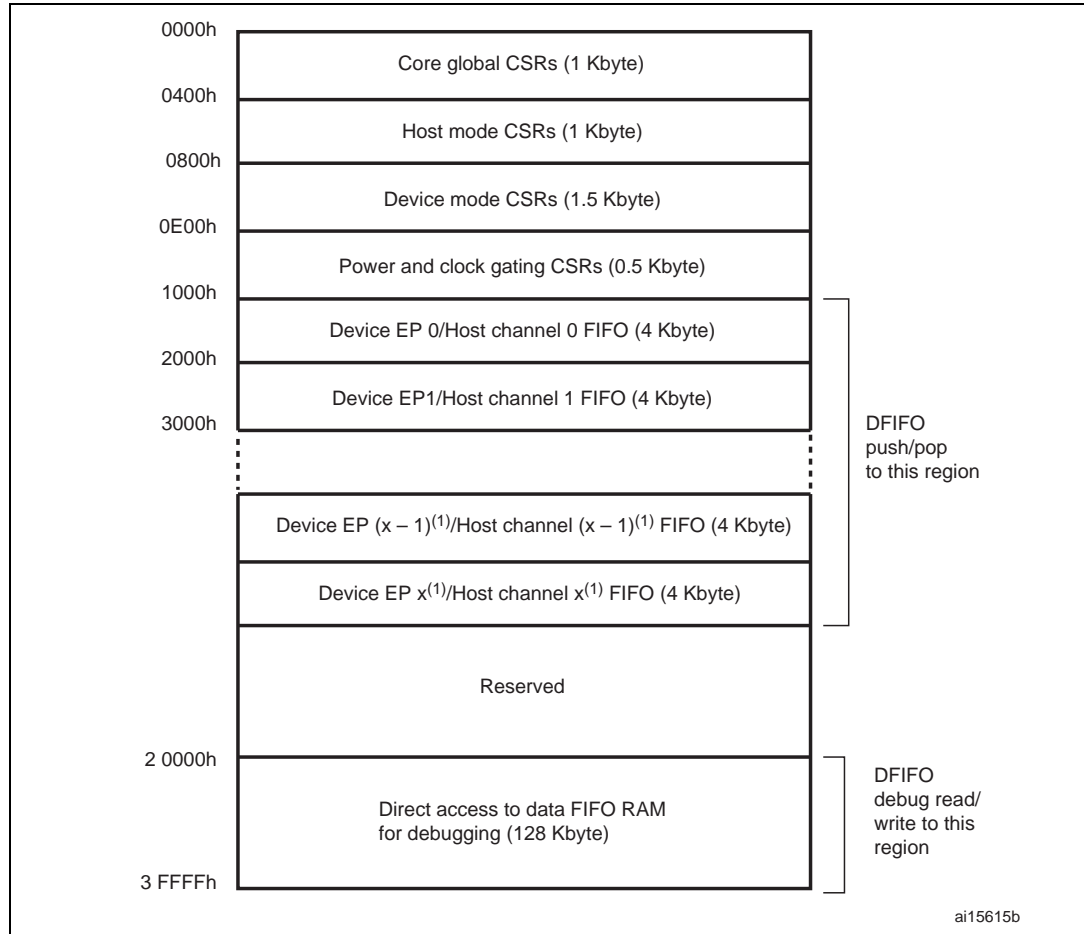
- Host port CSRs
- Host channel-specific registers
- Device-mode registers
- Device global registers
- Device endpoint-specific registers
- Power and clock-gating registers
- Data FIFO (DFIFO) access registers

Only the Core global, Power and clock-gating, Data FIFO access, and host port control and status registers can be accessed in both host and device modes. When the OTG\_FS controller is operating in one mode, either device or host, the application must not access registers from the other mode. If an illegal access occurs, a mode mismatch interrupt is generated and reflected in the Core interrupt register (MMIS bit in the OTG\_FS\_GINTSTS register). When the core switches from one mode to the other, the registers in the new mode of operation must be reprogrammed as they would be after a power-on reset.

### 22.16.1 CSR memory map

The host and device mode registers occupy different addresses. All registers are implemented in the AHB clock domain.

**Figure 251. CSR memory map**



1. x = 3 in device mode and x = 7 in host mode.

#### Global CSR map

These registers are available in both host and device modes.

**Table 126. Core global control and status registers (CSRs)**

Acronym	Address offset	Register name
OTG_FS_GOTGCTL	0x000	<i>OTG_FS control and status register (OTG_FS_GOTGCTL) on page 693</i>
OTG_FS_GOTGINT	0x004	<i>OTG_FS interrupt register (OTG_FS_GOTGINT) on page 695</i>
OTG_FS_GAHBCFG	0x008	<i>OTG_FS AHB configuration register (OTG_FS_GAHBCFG) on page 696</i>
OTG_FS_GUSBCFG	0x00C	<i>OTG_FS USB configuration register (OTG_FS_GUSBCFG) on page 697</i>
OTG_FS_GRSTCTL	0x010	<i>OTG_FS reset register (OTG_FS_GRSTCTL) on page 699</i>

**Table 126. Core global control and status registers (CSRs) (continued)**

Acronym	Address offset	Register name
OTG_FS_GINTSTS	0x014	<i>OTG_FS core interrupt register (OTG_FS_GINTSTS) on page 701</i>
OTG_FS_GINTMSK	0x018	<i>OTG_FS interrupt mask register (OTG_FS_GINTMSK) on page 705</i>
OTG_FS_GRXSTSR	0x01C	<i>OTG_FS Receive status debug read/OTG status read and pop registers (OTG_FS_GRXSTSR/OTG_FS_GRXSTSP) on page 708</i>
OTG_FS_GRXSTSP	0x020	
OTG_FS_GRXFSIZ	0x024	<i>OTG_FS Receive FIFO size register (OTG_FS_GRXFSIZ) on page 709</i>
OTG_FS_HNPTXFSIZ/ OTG_FS_DIEPTXF0 <sup>(1)</sup>	0x028	<i>OTG_FS Host non-periodic transmit FIFO size register (OTG_FS_HNPTXFSIZ)/Endpoint 0 Transmit FIFO size (OTG_FS_DIEPTXF0)</i>
OTG_FS_HNPTXSTS	0x02C	<i>OTG_FS non-periodic transmit FIFO/queue status register (OTG_FS_HNPTXSTS) on page 710</i>
OTG_FS_GCCFG	0x038	<i>OTG_FS general core configuration register (OTG_FS_GCCFG) on page 711</i>
OTG_FS_CID	0x03C	<i>OTG_FS core ID register (OTG_FS_CID) on page 712</i>
OTG_FS_HPTXFSIZ	0x100	<i>OTG_FS Host periodic transmit FIFO size register (OTG_FS_HPTXFSIZ) on page 713</i>
OTG_FS_DIEPTFXx	0x104 0x124 ... 0x138	<i>OTG_FS device IN endpoint transmit FIFO size register (OTG_FS_DIEPTFXx) (x = 1..3, where x is the FIFO_number) on page 713</i>

1. The general rule is to use OTG\_FS\_HNPTXFSIZ for host mode and OTG\_FS\_DIEPTXF0 for device mode.

**Host-mode CSR map**

These registers must be programmed every time the core changes to host mode.

**Table 127. Host-mode control and status registers (CSRs)**

Acronym	Offset address	Register name
OTG_FS_HCFG	0x400	<i>OTG_FS Host configuration register (OTG_FS_HCFG) on page 714</i>
OTG_FS_HFIR	0x404	<i>OTG_FS Host frame interval register (OTG_FS_HFIR) on page 714</i>
OTG_FS_HFNUM	0x408	<i>OTG_FS Host frame number/frame time remaining register (OTG_FS_HFNUM) on page 715</i>
OTG_FS_HPTXSTS	0x410	<i>OTG_FS Host periodic transmit FIFO/queue status register (OTG_FS_HPTXSTS) on page 715</i>
OTG_FS_HAINT	0x414	<i>OTG_FS Host all channels interrupt register (OTG_FS_HAINT) on page 716</i>
OTG_FS_HAINTMSK	0x418	<i>OTG_FS Host all channels interrupt mask register (OTG_FS_HAINTMSK) on page 717</i>

**Table 127. Host-mode control and status registers (CSRs) (continued)**

Acronym	Offset address	Register name
OTG_FS_HPRT	0x440	<i>OTG_FS Host port control and status register (OTG_FS_HPRT) on page 717</i>
OTG_FS_HCCHARx	0x500 0x520 ... 0x6E0h	<i>OTG_FS Host channel-x characteristics register (OTG_FS_HCCHARx) (x = 0..7, where x = Channel_number) on page 720</i>
OTG_FS_HCINTx	508h	<i>OTG_FS Host channel-x interrupt register (OTG_FS_HCINTx) (x = 0..7, where x = Channel_number) on page 721</i>
OTG_FS_HCINTMSKx	50Ch	<i>OTG_FS Host channel-x interrupt mask register (OTG_FS_HCINTMSKx) (x = 0..7, where x = Channel_number) on page 722</i>
OTG_FS_HCTSIZx	510h	<i>OTG_FS Host channel-x transfer size register (OTG_FS_HCTSIZx) (x = 0..7, where x = Channel_number) on page 723</i>

**Device-mode CSR map**

These registers must be programmed every time the core changes to device mode.

**Table 128. Device-mode control and status registers**

Acronym	Offset address	Register name
OTG_FS_DCFG	0x800	<i>OTG_FS device configuration register (OTG_FS_DCFG) on page 724</i>
OTG_FS_DCTL	0x804	<i>OTG_FS device control register (OTG_FS_DCTL) on page 725</i>
OTG_FS_DSTS	0x808	<i>OTG_FS device status register (OTG_FS_DSTS) on page 726</i>
OTG_FS_DIEPMSK	0x810	<i>OTG_FS device IN endpoint common interrupt mask register (OTG_FS_DIEPMSK) on page 727</i>
OTG_FS_DOEPMSK	0x814	<i>OTG_FS device OUT endpoint common interrupt mask register (OTG_FS_DOEPMSK) on page 728</i>
OTG_FS_DAIN	0x818	<i>OTG_FS device all endpoints interrupt register (OTG_FS_DAIN) on page 729</i>
OTG_FS_DAINMSK	0x81C	<i>OTG_FS all endpoints interrupt mask register (OTG_FS_DAINMSK) on page 729</i>
OTG_FS_DVBUSDIS	0x828	<i>OTG_FS device VBUS discharge time register (OTG_FS_DVBUSDIS) on page 730</i>
OTG_FS_DVBUSPULSE	0x82C	<i>OTG_FS device VBUS pulsing time register (OTG_FS_DVBUSPULSE) on page 730</i>
OTG_FS_DIEPEMPMSK	0x834	<i>OTG_FS device IN endpoint FIFO empty interrupt mask register: (OTG_FS_DIEPEMPMSK) on page 730</i>
OTG_FS_DIEPCTL0	0x900	<i>OTG_FS device control IN endpoint 0 control register (OTG_FS_DIEPCTL0) on page 731</i>

Table 128. Device-mode control and status registers (continued)

Acronym	Offset address	Register name
OTG_FS_DIEPCTLx	0x920 0x940 ... 0xAE0	OTG device endpoint-x control register (OTG_FS_DIEPCTLx) (x = 1..3, where x = Endpoint_number) on page 732
OTG_FS_DIEPINTx	0x908	OTG_FS device endpoint-x interrupt register (OTG_FS_DIEPINTx) (x = 0..3, where x = Endpoint_number) on page 739
OTG_FS_DIEPTSIZ0	0x910	OTG_FS device IN endpoint 0 transfer size register (OTG_FS_DIEPTSIZ0) on page 741
OTG_FS_DTXFSTSx	0x918	OTG_FS device IN endpoint transmit FIFO status register (OTG_FS_DTXFSTSx) (x = 0..3, where x = Endpoint_number) on page 744
OTG_FS_DIEPTSIZx	0x930 0x950 ... 0xAF0	OTG_FS device OUT endpoint-x transfer size register (OTG_FS_DIEPTSIZx) (x = 1..3, where x = Endpoint_number) on page 744
OTG_FS_DOEPCTL0	0xB00	OTG_FS device control OUT endpoint 0 control register (OTG_FS_DOEPCTL0) on page 735
OTG_FS_DOEPCTLx	0xB20 0xB40 ... 0xCC0 0xCE0 0xCFD	OTG device endpoint-x control register (OTG_FS_DIEPCTLx) (x = 1..3, where x = Endpoint_number) on page 732
OTG_FS_DOEPINTx	0xB08	OTG_FS device endpoint-x interrupt register (OTG_FS_DIEPINTx) (x = 0..3, where x = Endpoint_number) on page 739
OTG_FS_DOEPTSIZx	0xB10	OTG_FS device OUT endpoint-x transfer size register (OTG_FS_DOEPTSIZx) (x = 1..3, where x = Endpoint_number) on page 744

### Data FIFO (DFIFO) access register map

These registers, available in both host and device modes, are used to read or write the FIFO space for a specific endpoint or a channel, in a given direction. If a host channel is of type IN, the FIFO can only be read on the channel. Similarly, if a host channel is of type OUT, the FIFO can only be written on the channel.



**Table 129. Data FIFO (DFIFO) access register map**

FIFO access register section	Address range	Access
Device IN Endpoint 0/Host OUT Channel 0: DFIFO Write Access Device OUT Endpoint 0/Host IN Channel 0: DFIFO Read Access	0x1000–0x1FFC	w r
Device IN Endpoint 1/Host OUT Channel 1: DFIFO Write Access Device OUT Endpoint 1/Host IN Channel 1: DFIFO Read Access	0x2000–0x2FFC	w r
...	...	...
Device IN Endpoint x <sup>(1)</sup> /Host OUT Channel x <sup>(1)</sup> : DFIFO Write Access Device OUT Endpoint x <sup>(1)</sup> /Host IN Channel x <sup>(1)</sup> : DFIFO Read Access	0xX000–0xXFFC	w r

1. Where x is 3 in device mode and 7 in host mode.

**Power and clock gating CSR map**

There is a single register for power and clock gating. It is available in both host and device modes.

**Table 130. Power and clock gating control and status registers**

Register name	Acronym	Offset address: 0xE00–0xFFF
Power and clock gating control register	PCGCR	0xE00-0xE04
Reserved		0xE05–0xFFF

### 22.16.2 OTG\_FS global registers

These registers are available in both host and device modes, and do not need to be reprogrammed when switching between these modes.

Bit values in the register descriptions are expressed in binary unless otherwise specified.

#### OTG\_FS control and status register (OTG\_FS\_GOTGCTL)

Address offset: 0x000

Reset value: 0x0000 0800

The OTG\_FS\_GOTGCTL register controls the behavior and reflects the status of the OTG function of the core.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved												BSVLD	ASVLD	DBCT	CIDSTS	Reserved				DHNPEN	HSHNPEN	HNPPO	HNGSCS	Reserved				SRQ	SRQSCS		
												r	r	r	r					rw	rw	rw	r					rw	r		

Bits 31:20 Reserved, must be kept at reset value.

Bit 19 **BSVLD**: B-session valid

Indicates the device mode transceiver status.

0: B-session is not valid.

1: B-session is valid.

In OTG mode, you can use this bit to determine if the device is connected or disconnected.

*Note: Only accessible in device mode.*

Bit 18 **ASVLD**: A-session valid

Indicates the host mode transceiver status.

0: A-session is not valid

1: A-session is valid

*Note: Only accessible in host mode.*

Bit 17 **DBCT**: Long/short debounce time

Indicates the debounce time of a detected connection.

0: Long debounce time, used for physical connections (100 ms + 2.5 μs)

1: Short debounce time, used for soft connections (2.5 μs)

*Note: Only accessible in host mode.*

Bit 16 **CIDSTS**: Connector ID status

Indicates the connector ID status on a connect event.

0: The OTG\_FS controller is in A-device mode

1: The OTG\_FS controller is in B-device mode

*Note: Accessible in both device and host modes.*

Bits 15:12 Reserved, must be kept at reset value.

- Bit 11 **DHNPEN**: Device HNP enabled  
The application sets this bit when it successfully receives a SetFeature.SetHNPEnable command from the connected USB host.  
0: HNP is not enabled in the application  
1: HNP is enabled in the application  
*Note: Only accessible in device mode.*
- Bit 10 **HSHNPEN**: host set HNP enable  
The application sets this bit when it has successfully enabled HNP (using the SetFeature.SetHNPEnable command) on the connected device.  
0: Host Set HNP is not enabled  
1: Host Set HNP is enabled  
*Note: Only accessible in host mode.*
- Bit 9 **HNPRQ**: HNP request  
The application sets this bit to initiate an HNP request to the connected USB host. The application can clear this bit by writing a 0 when the host negotiation success status change bit in the OTG\_FS\_GOTGINT register (HNSSCHG bit in OTG\_FS\_GOTGINT) is set. The core clears this bit when the HNSSCHG bit is cleared.  
0: No HNP request  
1: HNP request  
*Note: Only accessible in device mode.*
- Bit 8 **HNGSCS**: Host negotiation success  
The core sets this bit when host negotiation is successful. The core clears this bit when the HNP Request (HNPRQ) bit in this register is set.  
0: Host negotiation failure  
1: Host negotiation success  
*Note: Only accessible in device mode.*
- Bits 7:2 Reserved, must be kept at reset value.
- Bit 1 **SRQ**: Session request  
The application sets this bit to initiate a session request on the USB. The application can clear this bit by writing a 0 when the host negotiation success status change bit in the OTG\_FS\_GOTGINT register (HNSSCHG bit in OTG\_FS\_GOTGINT) is set. The core clears this bit when the HNSSCHG bit is cleared.  
If you use the USB 1.1 full-speed serial transceiver interface to initiate the session request, the application must wait until  $V_{BUS}$  discharges to 0.2 V, after the B-Session Valid bit in this register (BSVLD bit in OTG\_FS\_GOTGCTL) is cleared. This discharge time varies between different PHYs and can be obtained from the PHY vendor.  
0: No session request  
1: Session request  
*Note: Only accessible in device mode.*
- Bit 0 **SRQSCS**: Session request success  
The core sets this bit when a session request initiation is successful.  
0: Session request failure  
1: Session request success  
*Note: Only accessible in device mode.*

### OTG\_FS interrupt register (OTG\_FS\_GOTGINT)

Address offset: 0x04

Reset value: 0x0000 0000

The application reads this register whenever there is an OTG interrupt and clears the bits in this register to clear the OTG interrupt.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0		
Reserved												DBCNE	ADTOCHG	HNGDET	Reserved												HNSSCHG	SRSSCHG	Reserved			SEDET	Res.
												rc_w1	rc_w1	rc_w1													rc_w1	rc_w1				rc_w1	

Bits 31:20 Reserved, must be kept at reset value.

Bit 19 **DBCNE**: Debounce done

The core sets this bit when the debounce is completed after the device connect. The application can start driving USB reset after seeing this interrupt. This bit is only valid when the HNP Capable or SRP Capable bit is set in the OTG\_FS\_GUSBCFG register (HNPCAP bit or SRPCAP bit in OTG\_FS\_GUSBCFG, respectively).

*Note: Only accessible in host mode.*

Bit 18 **ADTOCHG**: A-device timeout change

The core sets this bit to indicate that the A-device has timed out while waiting for the B-device to connect.

*Note: Accessible in both device and host modes.*

Bit 17 **HNGDET**: Host negotiation detected

The core sets this bit when it detects a host negotiation request on the USB.

*Note: Accessible in both device and host modes.*

Bits 16:10 Reserved, must be kept at reset value.

Bit 9 **HNSSCHG**: Host negotiation success status change

The core sets this bit on the success or failure of a USB host negotiation request. The application must read the host negotiation success bit of the OTG\_FS\_GOTGCTL register (HNGSCS in OTG\_FS\_GOTGCTL) to check for success or failure.

*Note: Accessible in both device and host modes.*

Bits 7:3 Reserved, must be kept at reset value.

Bit 8 **SRSSCHG**: Session request success status change

The core sets this bit on the success or failure of a session request. The application must read the session request success bit in the OTG\_FS\_GOTGCTL register (SRQSCS bit in OTG\_FS\_GOTGCTL) to check for success or failure.

*Note: Accessible in both device and host modes.*

Bit 2 **SEDET**: Session end detected

The core sets this bit to indicate that the level of the voltage on  $V_{BUS}$  is no longer valid for a B-Peripheral session when  $V_{BUS} < 0.8$  V.

Bits 1:0 Reserved, must be kept at reset value.

**OTG\_FS AHB configuration register (OTG\_FS\_GAHBCFG)**

Address offset: 0x008

Reset value: 0x0000 0000

This register can be used to configure the core after power-on or a change in mode. This register mainly contains AHB system-related configuration parameters. Do not change this register after the initial programming. The application must program this register before starting any transactions on either the AHB or the USB.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved																							PTXFELVL	TXFELVL	Reserved			GINTMSK			
																							rw	rw				rw			

Bits 31:20 Reserved, must be kept at reset value.

**Bit 8 PTXFELVL:** Periodic Tx FIFO empty level

Indicates when the periodic Tx FIFO empty interrupt bit in the OTG\_FS\_GINTSTS register (PTXFE bit in OTG\_FS\_GINTSTS) is triggered.

- 0: PTXFE (in OTG\_FS\_GINTSTS) interrupt indicates that the Periodic Tx FIFO is half empty
- 1: PTXFE (in OTG\_FS\_GINTSTS) interrupt indicates that the Periodic Tx FIFO is completely empty

*Note: Only accessible in host mode.*

**Bit 7 TXFELVL:** Tx FIFO empty level

In device mode, this bit indicates when IN endpoint Transmit FIFO empty interrupt (TXFE in OTG\_FS\_DIEPINTx) is triggered.

- 0: the TXFE (in OTG\_FS\_DIEPINTx) interrupt indicates that the IN Endpoint Tx FIFO is half empty
- 1: the TXFE (in OTG\_FS\_DIEPINTx) interrupt indicates that the IN Endpoint Tx FIFO is completely empty

In host mode, this bit indicates when the nonperiodic Tx FIFO empty interrupt (NPTXFE bit in OTG\_FS\_GINTSTS) is triggered:

- 0: the NPTXFE (in OTG\_FS\_GINTSTS) interrupt indicates that the nonperiodic Tx FIFO is half empty
- 1: the NPTXFE (in OTG\_FS\_GINTSTS) interrupt indicates that the nonperiodic Tx FIFO is completely empty

Bits 6:1 Reserved, must be kept at reset value.

**Bit 0 GINTMSK:** Global interrupt mask

The application uses this bit to mask or unmask the interrupt line assertion to itself. Irrespective of this bit's setting, the interrupt status registers are updated by the core.

- 0: Mask the interrupt assertion to the application.
- 1: Unmask the interrupt assertion to the application.

*Note: Accessible in both device and host modes.*

**OTG\_FS USB configuration register (OTG\_FS\_GUSBCFG)**

Address offset: 0x00C

Reset value: 0x0000 0A00

This register can be used to configure the core after power-on or a changing to host mode or device mode. It contains USB and USB-PHY related configuration parameters. The application must program this register before starting any transactions on either the AHB or the USB. Do not make changes to this register after the initial programming.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
CTXPKT	FDMOD	FHMOD	Reserved														TRDT	HNPCAP	SRPCAP	Res.	PHYSEL	Reserved			TOCAL						
rw	rw	rw															rw	r/w	r/w		wo				rw						

Bits 31:20 Reserved, must be kept at reset value.

Bit 31 **CTXPKT**: Corrupt Tx packet

This bit is for debug purposes only. Never set this bit to 1.

*Note: Accessible in both device and host modes.*

Bit 30 **FDMOD**: Force device mode

Writing a 1 to this bit forces the core to device mode irrespective of the OTG\_FS\_ID input pin.

0: Normal mode

1: Force device mode

After setting the force bit, the application must wait at least 25 ms before the change takes effect.

*Note: Accessible in both device and host modes.*

Bit 29 **FHMOD**: Force host mode

Writing a 1 to this bit forces the core to host mode irrespective of the OTG\_FS\_ID input pin.

0: Normal mode

1: Force host mode

After setting the force bit, the application must wait at least 25 ms before the change takes effect.

*Note: Accessible in both device and host modes.*

Bits 28:14 Reserved, must be kept at reset value.

Bits 13:10 **TRDT**: USB turnaround time

These bits allows to set the turnaround time in PHY clocks. They must be configured according to [Table 131: TRDT values](#), depending on the application AHB frequency. Higher TRDT values allow stretching the USB response time to IN tokens in order to compensate for longer AHB read access latency to the Data FIFO.

*Note: Only accessible in device mode.*

Bit 9 **HNPCAP**: HNP-capable

The application uses this bit to control the OTG\_FS controller's HNP capabilities.

0: HNP capability is not enabled.

1: HNP capability is enabled.

*Note: Accessible in both device and host modes.*



Bit 8 **SRPCAP**: SRP-capable

The application uses this bit to control the OTG\_FS controller's SRP capabilities. If the core operates as a non-SRP-capable B-device, it cannot request the connected A-device (host) to activate  $V_{BUS}$  and start a session.

0: SRP capability is not enabled.

1: SRP capability is enabled.

*Note: Accessible in both device and host modes.*

Bit 7 Reserved, must be kept at reset value.

Bit 6 **PHYSEL**: Full Speed serial transceiver select

This bit is always 1 with write-only access.

Bits 5:3 Reserved, must be kept at reset value.

Bits 2:0 **TOCAL**: FS timeout calibration

The number of PHY clocks that the application programs in this field is added to the full-speed interpacket timeout duration in the core to account for any additional delays introduced by the PHY. This can be required, because the delay introduced by the PHY in generating the line state condition can vary from one PHY to another.

The USB standard timeout value for full-speed operation is 16 to 18 (inclusive) bit times. The application must program this field based on the speed of enumeration. The number of bit times added per PHY clock is 0.25 bit times.

**Table 131. TRDT values**

AHB frequency range (MHz)		TRDT minimum value
Min.	Max	
14.2	15	0xF
15	16	0xE
16	17.2	0xD
17.2	18.5	0xC
18.5	20	0xB
20	21.8	0xA
21.8	24	0x9
24	27.5	0x8
27.5	32	0x7
32	-	0x6

### OTG\_FS reset register (OTG\_FS\_GRSTCTL)

Address offset: 0x10

Reset value: 0x2000 0000

The application uses this register to reset various hardware features inside the core.

	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
AHBIDL	Reserved															TXFNUM			TXFFLSH	RXFFLSH	Reserved	FCRST	HSRST	CSRST								
r																rw			rs	rs		rs	rs	rs								

Bit 31 **AHBIDL**: AHB master idle

Indicates that the AHB master state machine is in the Idle condition.

*Note: Accessible in both device and host modes.*

Bits 30:11 Reserved, must be kept at reset value.

Bits 10:6 **TXFNUM**: TxFIFO number

This is the FIFO number that must be flushed using the TxFIFO Flush bit. This field must not be changed until the core clears the TxFIFO Flush bit.

00000:

- Non-periodic TxFIFO flush in host mode
- Tx FIFO 0 flush in device mode

00001:

- Periodic TxFIFO flush in host mode
- TXFIFO 1 flush in device mode

00010: TXFIFO 2 flush in device mode

...

00101: TXFIFO 15 flush in device mode

10000: Flush all the transmit FIFOs in device or host mode.

*Note: Accessible in both device and host modes.*

Bit 5 **TXFFLSH**: TxFIFO flush

This bit selectively flushes a single or all transmit FIFOs, but cannot do so if the core is in the midst of a transaction.

The application must write this bit only after checking that the core is neither writing to the TxFIFO nor reading from the TxFIFO. Verify using these registers:

Read—NAK Effective Interrupt ensures the core is not reading from the FIFO

Write—AHBIDL bit in OTG\_FS\_GRSTCTL ensures the core is not writing anything to the FIFO.

*Note: Accessible in both device and host modes.*

Bit 4 **RXFFLSH**: RxFIFO flush

The application can flush the entire RxFIFO using this bit, but must first ensure that the core is not in the middle of a transaction.

The application must only write to this bit after checking that the core is neither reading from the RxFIFO nor writing to the RxFIFO.

The application must wait until the bit is cleared before performing any other operations. This bit requires 8 clocks (slowest of PHY or AHB clock) to clear.

*Note: Accessible in both device and host modes.*

Bit 3 Reserved, must be kept at reset value.





**Bit 2 FCRST:** Host frame counter reset

The application writes this bit to reset the frame number counter inside the core. When the frame counter is reset, the subsequent SOF sent out by the core has a frame number of 0.

*Note:* Only accessible in host mode.

**Bit 1 HSRST:** HCLK soft reset

The application uses this bit to flush the control logic in the AHB Clock domain. Only AHB Clock Domain pipelines are reset.

FIFOs are not flushed with this bit.

All state machines in the AHB clock domain are reset to the Idle state after terminating the transactions on the AHB, following the protocol.

CSR control bits used by the AHB clock domain state machines are cleared.

To clear this interrupt, status mask bits that control the interrupt status and are generated by the AHB clock domain state machine are cleared.

Because interrupt status bits are not cleared, the application can get the status of any core events that occurred after it set this bit.

This is a self-clearing bit that the core clears after all necessary logic is reset in the core. This can take several clocks, depending on the core's current state.

*Note:* Accessible in both device and host modes.

**Bit 0 CSRST:** Core soft reset

Resets the HCLK and PCLK domains as follows:

Clears the interrupts and all the CSR register bits except for the following bits:

- RSTPDMODL bit in OTG\_FS\_PCGCCTL
- GAYEHCLK bit in OTG\_FS\_PCGCCTL
- PWRCLMP bit in OTG\_FS\_PCGCCTL
- STPPCLK bit in OTG\_FS\_PCGCCTL
- FSLSPCS bit in OTG\_FS\_HCFG
- DSPD bit in OTG\_FS\_DCFG

All module state machines (except for the AHB slave unit) are reset to the Idle state, and all the transmit FIFOs and the receive FIFO are flushed.

Any transactions on the AHB Master are terminated as soon as possible, after completing the last data phase of an AHB transfer. Any transactions on the USB are terminated immediately.

The application can write to this bit any time it wants to reset the core. This is a self-clearing bit and the core clears this bit after all the necessary logic is reset in the core, which can take several clocks, depending on the current state of the core. Once this bit has been cleared, the software must wait at least 3 PHY clocks before accessing the PHY domain (synchronization delay). The software must also check that bit 31 in this register is set to 1 (AHB Master is Idle) before starting any operation.

Typically, the software reset is used during software development and also when you dynamically change the PHY selection bits in the above listed USB configuration registers. When you change the PHY, the corresponding clock for the PHY is selected and used in the PHY domain. Once a new clock is selected, the PHY domain has to be reset for proper operation.

*Note:* Accessible in both device and host modes.

### OTG\_FS core interrupt register (OTG\_FS\_GINTSTS)

Address offset: 0x014

Reset value: 0x0400 0020

This register interrupts the application for system-level events in the current mode (device mode or host mode).

Some of the bits in this register are valid only in host mode, while others are valid in device mode only. This register also indicates the current mode. To clear the interrupt status bits of the rc\_w1 type, the application must write 1 into the bit.

The FIFO status interrupts are read-only; once software reads from or writes to the FIFO while servicing these interrupts, FIFO interrupt conditions are cleared automatically.

The application must clear the OTG\_FS\_GINTSTS register at initialization before unmasking the interrupt bit to avoid any interrupts generated prior to initialization.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
WKUINT	SRQINT	DISCINT	CIDSCHG	Reserved	PTXFE	HCINT	HPRTINT	Reserved	IPXFR/INCOMPISOOUT	IISOXFR	OEPIINT	IEPIINT	Reserved	EOFP	ISOODRP	ENUMDNE	USBRST	USBSUSP	ESUSP	Reserved	GOUTNAKEFF	GINAKEFF	NPTXFE	RXFLVL	SOF	OTGINT	MMIS	CMOD			
rc_w1					r	r	r	Res.	rc_w1		r	r		rc_w1							r	r	r	r	rc_w1		r	rc_w1		r	

- Bit 31 WKUPOINT:** Resume/remote wakeup detected interrupt  
 In device mode, this interrupt is asserted when a resume is detected on the USB. In host mode, this interrupt is asserted when a remote wakeup is detected on the USB.  
*Note: Accessible in both device and host modes.*
- Bit 30 SRQINT:** Session request/new session detected interrupt  
 In host mode, this interrupt is asserted when a session request is detected from the device. In device mode, this interrupt is asserted when  $V_{BUS}$  is in the valid range for a B-peripheral device. Accessible in both device and host modes.
- Bit 29 DISCINT:** Disconnect detected interrupt  
 Asserted when a device disconnect is detected.  
*Note: Only accessible in host mode.*
- Bit 28 CIDSCHG:** Connector ID status change  
 The core sets this bit when there is a change in connector ID status.  
*Note: Accessible in both device and host modes.*
- Bit 27** Reserved, must be kept at reset value.
- Bit 26 PTXFE:** Periodic Tx FIFO empty  
 Asserted when the periodic transmit FIFO is either half or completely empty and there is space for at least one entry to be written in the periodic request queue. The half or completely empty status is determined by the periodic Tx FIFO empty level bit in the OTG\_FS\_GAHBCFG register (PTXFELVL bit in OTG\_FS\_GAHBCFG).  
*Note: Only accessible in host mode.*



- Bit 25 **HCINT**: Host channels interrupt  
The core sets this bit to indicate that an interrupt is pending on one of the channels of the core (in host mode). The application must read the OTG\_FS\_HAINT register to determine the exact number of the channel on which the interrupt occurred, and then read the corresponding OTG\_FS\_HCINTx register to determine the exact cause of the interrupt. The application must clear the appropriate status bit in the OTG\_FS\_HCINTx register to clear this bit.  
*Note: Only accessible in host mode.*
- Bit 24 **HPRTINT**: Host port interrupt  
The core sets this bit to indicate a change in port status of one of the OTG\_FS controller ports in host mode. The application must read the OTG\_FS\_HPRT register to determine the exact event that caused this interrupt. The application must clear the appropriate status bit in the OTG\_FS\_HPRT register to clear this bit.  
*Note: Only accessible in host mode.*
- Bits 23:22 Reserved, must be kept at reset value.
- Bit 21 **IPXFR**: Incomplete periodic transfer  
In host mode, the core sets this interrupt bit when there are incomplete periodic transactions still pending, which are scheduled for the current frame.  
**INCOMPISOOUT**: Incomplete isochronous OUT transfer  
In device mode, the core sets this interrupt to indicate that there is at least one isochronous OUT endpoint on which the transfer is not completed in the current frame. This interrupt is asserted along with the End of periodic frame interrupt (EOPF) bit in this register.
- Bit 20 **IISOIXFR**: Incomplete isochronous IN transfer  
The core sets this interrupt to indicate that there is at least one isochronous IN endpoint on which the transfer is not completed in the current frame. This interrupt is asserted along with the End of periodic frame interrupt (EOPF) bit in this register.  
*Note: Only accessible in device mode.*
- Bit 19 **OEPINT**: OUT endpoint interrupt  
The core sets this bit to indicate that an interrupt is pending on one of the OUT endpoints of the core (in device mode). The application must read the OTG\_FS\_DAIN register to determine the exact number of the OUT endpoint on which the interrupt occurred, and then read the corresponding OTG\_FS\_DOEPINTx register to determine the exact cause of the interrupt. The application must clear the appropriate status bit in the corresponding OTG\_FS\_DOEPINTx register to clear this bit.  
*Note: Only accessible in device mode.*
- Bit 18 **IEPINT**: IN endpoint interrupt  
The core sets this bit to indicate that an interrupt is pending on one of the IN endpoints of the core (in device mode). The application must read the OTG\_FS\_DAIN register to determine the exact number of the IN endpoint on which the interrupt occurred, and then read the corresponding OTG\_FS\_DIEPINTx register to determine the exact cause of the interrupt. The application must clear the appropriate status bit in the corresponding OTG\_FS\_DIEPINTx register to clear this bit.  
*Note: Only accessible in device mode.*
- Bits 17:16 Reserved, must be kept at reset value.
- Bit 15 **EOPF**: End of periodic frame interrupt  
Indicates that the period specified in the periodic frame interval field of the OTG\_FS\_DCFG register (PFIVL bit in OTG\_FS\_DCFG) has been reached in the current frame.  
*Note: Only accessible in device mode.*

- Bit 14 **ISOODRP**: Isochronous OUT packet dropped interrupt  
The core sets this bit when it fails to write an isochronous OUT packet into the RxFIFO because the RxFIFO does not have enough space to accommodate a maximum size packet for the isochronous OUT endpoint.  
*Note: Only accessible in device mode.*
- Bit 13 **ENUMDNE**: Enumeration done  
The core sets this bit to indicate that speed enumeration is complete. The application must read the OTG\_FS\_DSTS register to obtain the enumerated speed.  
*Note: Only accessible in device mode.*
- Bit 12 **USBRST**: USB reset  
The core sets this bit to indicate that a reset is detected on the USB.  
*Note: Only accessible in device mode.*
- Bit 11 **USBSUSP**: USB suspend  
The core sets this bit to indicate that a suspend was detected on the USB. The core enters the Suspended state when there is no activity on the data lines for a period of 3 ms.  
*Note: Only accessible in device mode.*
- Bit 10 **ESUSP**: Early suspend  
The core sets this bit to indicate that an Idle state has been detected on the USB for 3 ms.  
*Note: Only accessible in device mode.*
- Bits 9:8 Reserved, must be kept at reset value.
- Bit 7 **GONAKEFF**: Global OUT NAK effective  
Indicates that the Set global OUT NAK bit in the OTG\_FS\_DCTL register (SGONAK bit in OTG\_FS\_DCTL), set by the application, has taken effect in the core. This bit can be cleared by writing the Clear global OUT NAK bit in the OTG\_FS\_DCTL register (CGONAK bit in OTG\_FS\_DCTL).  
*Note: Only accessible in device mode.*
- Bit 6 **GINAKEFF**: Global IN non-periodic NAK effective  
Indicates that the Set global non-periodic IN NAK bit in the OTG\_FS\_DCTL register (SGINAK bit in OTG\_FS\_DCTL), set by the application, has taken effect in the core. That is, the core has sampled the Global IN NAK bit set by the application. This bit can be cleared by clearing the Clear global non-periodic IN NAK bit in the OTG\_FS\_DCTL register (CGINAK bit in OTG\_FS\_DCTL).  
This interrupt does not necessarily mean that a NAK handshake is sent out on the USB. The STALL bit takes precedence over the NAK bit.  
*Note: Only accessible in device mode.*
- Bit 5 **NPTXFE**: Non-periodic TxFIFO empty  
This interrupt is asserted when the non-periodic TxFIFO is either half or completely empty, and there is space for at least one entry to be written to the non-periodic transmit request queue. The half or completely empty status is determined by the non-periodic TxFIFO empty level bit in the OTG\_FS\_GAHBCFG register (TXFELVL bit in OTG\_FS\_GAHBCFG).  
*Note: Accessible in host mode only.*
- Bit 4 **RXFLVL**: RxFIFO non-empty  
Indicates that there is at least one packet pending to be read from the RxFIFO.  
*Note: Accessible in both host and device modes.*

**Bit 3 SOF:** Start of frame

In host mode, the core sets this bit to indicate that an SOF (FS), or Keep-Alive (LS) is transmitted on the USB. The application must write a 1 to this bit to clear the interrupt.

In device mode, the core sets this bit to indicate that an SOF token has been received on the USB. The application can read the Device Status register to get the current frame number. This interrupt is seen only when the core is operating in FS.

*Note: Accessible in both host and device modes.*

**Bit 2 OTGINT:** OTG interrupt

The core sets this bit to indicate an OTG protocol event. The application must read the OTG Interrupt Status (OTG\_FS\_GOTGINT) register to determine the exact event that caused this interrupt. The application must clear the appropriate status bit in the OTG\_FS\_GOTGINT register to clear this bit.

*Note: Accessible in both host and device modes.*

**Bit 1 MMIS:** Mode mismatch interrupt

The core sets this bit when the application is trying to access:

- A host mode register, when the core is operating in device mode
- A device mode register, when the core is operating in host mode

The register access is completed on the AHB with an OKAY response, but is ignored by the core internally and does not affect the operation of the core.

*Note: Accessible in both host and device modes.*

**Bit 0 CMOD:** Current mode of operation

Indicates the current mode.

0: Device mode

1: Host mode

*Note: Accessible in both host and device modes.*

**OTG\_FS interrupt mask register (OTG\_FS\_GINTMSK)**

Address offset: 0x018

Reset value: 0x0000 0000

This register works with the Core interrupt register to interrupt the application. When an interrupt bit is masked, the interrupt associated with that bit is not generated. However, the Core Interrupt (OTG\_FS\_GINTSTS) register bit corresponding to that interrupt is still set.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
WUIM	SRQIM	DISCINT	CIDSCHGM	Reserved	PTXFEM	HCIM	PRTIM	Reserved	IPXFRM/IISOXFRM	IISOXFRM	OEPINT	IEPINT	EPMISM	Reserved	EOPFM	ISOODRPM	ENUMDNEM	USBRST	USBSUSPM	ESUSPM	Reserved	GONAKEFFM	GINAKEFFM	NPTXFEM	RXFLVLM	SOFM	OTGINT	MMISM	Reserved		
rw	rw	rw	rw		rw	rw	r		rw	rw	rw	rw	rw		rw	rw	rw	rw	rw	rw		rw	rw	rw	rw	rw	rw	rw	rw		

Bit 31 **WUIM**: Resume/remote wakeup detected interrupt mask

- 0: Masked interrupt
- 1: Unmasked interrupt

*Note: Accessible in both host and device modes.*

Bit 30 **SRQIM**: Session request/new session detected interrupt mask

- 0: Masked interrupt
- 1: Unmasked interrupt

*Note: Accessible in both host and device modes.*

Bit 29 **DISCINT**: Disconnect detected interrupt mask

- 0: Masked interrupt
- 1: Unmasked interrupt

*Note: Only accessible in device mode.*

Bit 28 **CIDSCHGM**: Connector ID status change mask

- 0: Masked interrupt
- 1: Unmasked interrupt

*Note: Accessible in both host and device modes.*

Bit 27 Reserved, must be kept at reset value.

Bit 26 **PTXFEM**: Periodic Tx FIFO empty mask

- 0: Masked interrupt
- 1: Unmasked interrupt

*Note: Only accessible in host mode.*

Bit 25 **HCIM**: Host channels interrupt mask

- 0: Masked interrupt
- 1: Unmasked interrupt

*Note: Only accessible in host mode.*

Bit 24 **PRTIM**: Host port interrupt mask

- 0: Masked interrupt
- 1: Unmasked interrupt

*Note: Only accessible in host mode.*



- Bits 23:22 Reserved, must be kept at reset value.
- Bit 21 **IPXFRM**: Incomplete periodic transfer mask  
0: Masked interrupt  
1: Unmasked interrupt  
*Note: Only accessible in host mode.*
- IISOXFRM**: Incomplete isochronous OUT transfer mask  
0: Masked interrupt  
1: Unmasked interrupt  
*Note: Only accessible in device mode.*
- Bit 20 **IISOIXFRM**: Incomplete isochronous IN transfer mask  
0: Masked interrupt  
1: Unmasked interrupt  
*Note: Only accessible in device mode.*
- Bit 19 **OEPIINT**: OUT endpoints interrupt mask  
0: Masked interrupt  
1: Unmasked interrupt  
*Note: Only accessible in device mode.*
- Bit 18 **IEPIINT**: IN endpoints interrupt mask  
0: Masked interrupt  
1: Unmasked interrupt  
*Note: Only accessible in device mode.*
- Bit 17 **EPMISM**: Endpoint mismatch interrupt mask  
0: Masked interrupt  
1: Unmasked interrupt  
*Note: Only accessible in device mode.*
- Bit 16 Reserved, must be kept at reset value.
- Bit 15 **EOPFM**: End of periodic frame interrupt mask  
0: Masked interrupt  
1: Unmasked interrupt  
*Note: Only accessible in device mode.*
- Bit 14 **IISOODRPM**: Isochronous OUT packet dropped interrupt mask  
0: Masked interrupt  
1: Unmasked interrupt  
*Note: Only accessible in device mode.*
- Bit 13 **ENUMDNEM**: Enumeration done mask  
0: Masked interrupt  
1: Unmasked interrupt  
*Note: Only accessible in device mode.*
- Bit 12 **USBRST**: USB reset mask  
0: Masked interrupt  
1: Unmasked interrupt  
*Note: Only accessible in device mode.*

- Bit 11 **USBSUSPM**: USB suspend mask  
0: Masked interrupt  
1: Unmasked interrupt  
*Note: Only accessible in device mode.*
- Bit 10 **ESUSPM**: Early suspend mask  
0: Masked interrupt  
1: Unmasked interrupt  
*Note: Only accessible in device mode.*
- Bits 9:8 Reserved, must be kept at reset value.
- Bit 7 **GONAKEFFM**: Global OUT NAK effective mask  
0: Masked interrupt  
1: Unmasked interrupt  
*Note: Only accessible in device mode.*
- Bit 6 **GINAKEFFM**: Global non-periodic IN NAK effective mask  
0: Masked interrupt  
1: Unmasked interrupt  
*Note: Only accessible in device mode.*
- Bit 5 **NPTXFEM**: Non-periodic TxFIFO empty mask  
0: Masked interrupt  
1: Unmasked interrupt  
*Note: Only accessible in Host mode.*
- Bit 4 **RXFLVLM**: Receive FIFO non-empty mask  
0: Masked interrupt  
1: Unmasked interrupt  
*Note: Accessible in both device and host modes.*
- Bit 3 **SOFM**: Start of frame mask  
0: Masked interrupt  
1: Unmasked interrupt  
*Note: Accessible in both device and host modes.*
- Bit 2 **OTGINT**: OTG interrupt mask  
0: Masked interrupt  
1: Unmasked interrupt  
*Note: Accessible in both device and host modes.*
- Bit 1 **MMISM**: Mode mismatch interrupt mask  
0: Masked interrupt  
1: Unmasked interrupt  
*Note: Accessible in both device and host modes.*
- Bit 0 Reserved, must be kept at reset value.



**OTG\_FS Receive status debug read/OTG status read and pop registers (OTG\_FS\_GRXSTSR/OTG\_FS\_GRXSTSP)**

Address offset for Read: 0x01C

Address offset for Pop: 0x020

Reset value: 0x0000 0000

A read to the Receive status debug read register returns the contents of the top of the Receive FIFO. A read to the Receive status read and pop register additionally pops the top data entry out of the RxFIFO.

The receive status contents must be interpreted differently in host and device modes. The core ignores the receive status pop/read when the receive FIFO is empty and returns a value of 0x0000 0000. The application must only pop the Receive Status FIFO when the Receive FIFO non-empty bit of the Core interrupt register (RXFLVL bit in OTG\_FS\_GINTSTS) is asserted.

**Host mode**

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved											PKTSTS	DPID	BCNT						CHNUM												
											r	r	r						r												

Bits 31:21 **Reserved**, must be kept at reset value.

Bits 20:17 **PKTSTS**: Packet status

- Indicates the status of the received packet
- 0010: IN data packet received
- 0011: IN transfer completed (triggers an interrupt)
- 0101: Data toggle error (triggers an interrupt)
- 0111: Channel halted (triggers an interrupt)
- Others: Reserved

Bits 16:15 **DPID**: Data PID

- Indicates the Data PID of the received packet
- 00: DATA0
- 10: DATA1
- 01: DATA2
- 11: MDATA

Bits 14:4 **BCNT**: Byte count

Indicates the byte count of the received IN data packet.

Bits 3:0 **CHNUM**: Channel number

Indicates the channel number to which the current received packet belongs.

**Device mode**

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved							FRMNUM	PKTSTS	DPID	BCNT							EPNUM														
							r	r	r	r							r														

Bits 31:25 Reserved, must be kept at reset value.

Bits 24:21 **FRMNUM**: Frame number

This is the least significant 4 bits of the frame number in which the packet is received on the USB. This field is supported only when isochronous OUT endpoints are supported.

Bits 20:17 **PKTSTS**: Packet status

- Indicates the status of the received packet
- 0001: Global OUT NAK (triggers an interrupt)
- 0010: OUT data packet received
- 0011: OUT transfer completed (triggers an interrupt)
- 0100: SETUP transaction completed (triggers an interrupt)
- 0110: SETUP data packet received
- Others: Reserved

Bits 16:15 **DPID**: Data PID

- Indicates the Data PID of the received OUT data packet
- 00: DATA0
- 10: DATA1
- 01: DATA2
- 11: MDATA

Bits 14:4 **BCNT**: Byte count

Indicates the byte count of the received data packet.

Bits 3:0 **EPNUM**: Endpoint number

Indicates the endpoint number to which the current received packet belongs.

**OTG\_FS Receive FIFO size register (OTG\_FS\_GRXFSIZ)**

Address offset: 0x024

Reset value: 0x0000 0200

The application can program the RAM size that must be allocated to the Rx FIFO.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved																RXFD															
																r/rw															

Bits 31:16 Reserved, must be kept at reset value.

Bits 15:0 **RXFD**: Rx FIFO depth

- This value is in terms of 32-bit words.
- Minimum value is 16
- Maximum value is 256
- The power-on reset value of this register is specified as the largest Rx data FIFO depth.



**OTG\_FS Host non-periodic transmit FIFO size register  
(OTG\_FS\_HNPTXFSIZ)/Endpoint 0 Transmit FIFO size (OTG\_FS\_DIEPTXF0)**

Address offset: 0x028

Reset value: 0x0000 0200

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
NPTXFD/TX0FD																NPTXFSA/TX0FSA															
r/rw																r/rw															

Host mode

Bits 31:16 **NPTXFD**: Non-periodic TxFIFO depth  
 This value is in terms of 32-bit words.  
 Minimum value is 16  
 Maximum value is 256

Bits 15:0 **NPTXFSA**: Non-periodic transmit RAM start address  
 This field contains the memory start address for non-periodic transmit FIFO RAM.

Device mode

Bits 31:16 **TX0FD**: Endpoint 0 TxFIFO depth  
 This value is in terms of 32-bit words.  
 Minimum value is 16  
 Maximum value is 256

Bits 15:0 **TX0FSA**: Endpoint 0 transmit RAM start address  
 This field contains the memory start address for the endpoint 0 transmit FIFO RAM.

**OTG\_FS non-periodic transmit FIFO/queue status register  
(OTG\_FS\_HNPTXSTS)**

Address offset: 0x02C

Reset value: 0x0008 0200

*Note: In Device mode, this register is not valid.*

This read-only register contains the free space information for the non-periodic TxFIFO and the non-periodic transmit request queue.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved	NPTXQTOP								NPTQXSAV								NPTXFSAV														
	r								r								r														

- Bit 31 Reserved, must be kept at reset value.
- Bits 30:24 **NPTXQTOP**: Top of the non-periodic transmit request queue  
 Entry in the non-periodic Tx request queue that is currently being processed by the MAC.  
 Bits 30:27: Channel/endpoint number  
 Bits 26:25:  
  - 00: IN/OUT token
  - 01: Zero-length transmit packet (device IN/host OUT)
  - 11: Channel halt command
 Bit 24: Terminate (last entry for selected channel/endpoint)
- Bits 23:16 **NPTQXSAV**: Non-periodic transmit request queue space available  
 Indicates the amount of free space available in the non-periodic transmit request queue.  
 This queue holds both IN and OUT requests in host mode. Device mode has only IN requests.  
 00: Non-periodic transmit request queue is full  
 01: 1 location available  
 10: 2 locations available  
*bxn*: *n* locations available ( $0 \leq n \leq 8$ )  
 Others: Reserved
- Bits 15:0 **NPTXFSAV**: Non-periodic TxFIFO space available  
 Indicates the amount of free space available in the non-periodic TxFIFO.  
 Values are in terms of 32-bit words.  
 00: Non-periodic TxFIFO is full  
 01: 1 word available  
 10: 2 words available  
 0xn: *n* words available (where  $0 \leq n \leq 256$ )  
 Others: Reserved

**OTG\_FS general core configuration register (OTG\_FS\_GCCFG)**

Address offset: 0x038

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved										NOVBUSSENS	SOFOUTEN	VBUSBSEN	VBUSASEN	Reserved	.PWRDWN	Reserved															
										rw	rw	rw	rw	rw	rw																

Bits 31:22 Reserved, must be kept at reset value.

Bit 21 **NOVBUSSENS**: V<sub>BUS</sub> sensing disable option

When this bit is set, V<sub>BUS</sub> is considered internally to be always at V<sub>BUS</sub> valid level (5 V). This option removes the need for a dedicated V<sub>BUS</sub> pad, and leave this pad free to be used for other purposes such as a shared functionality. V<sub>BUS</sub> connection can be remapped on another general purpose input pad and monitored by software.

This option is only suitable for host-only or device-only applications.

0: V<sub>BUS</sub> sensing available by hardware

1: V<sub>BUS</sub> sensing not available by hardware.

Bit 20 **SOFOUTEN**: SOF output enable

0: SOF pulse not available on PAD

1: SOF pulse available on PAD

Bit 19 **VBUSBSEN**: Enable the V<sub>BUS</sub> sensing “B” device

0: V<sub>BUS</sub> sensing “B” disabled

1: V<sub>BUS</sub> sensing “B” enabled

Bit 18 **VBUSASEN**: Enable the V<sub>BUS</sub> sensing “A” device

0: V<sub>BUS</sub> sensing “A” disabled

1: V<sub>BUS</sub> sensing “A” enabled

Bit 17 Reserved, must be kept at reset value.

Bit 16 **PWRDWN**: Power down

Used to activate the transceiver in transmission/reception

0: Power down active

1: Power down deactivated (“Transceiver active”)

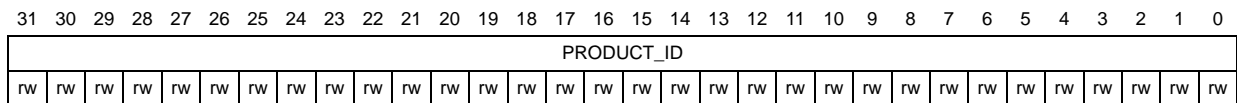
Bits 15:0 Reserved, must be kept at reset value.

### OTG\_FS core ID register (OTG\_FS\_CID)

Address offset: 0x03C

Reset value:0x0000 1100

This is a read only register containing the Product ID.



Bits 31:0 **PRODUCT\_ID**: Product ID field  
Application-programmable ID field.

**OTG\_FS Host periodic transmit FIFO size register (OTG\_FS\_HPTXFSIZ)**

Address offset: 0x100

Reset value: 0x0200 0600

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
PTXFSIZ																PTXSA															
r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r
w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w

Bits 31:16 **PTXFD**: Host periodic TxFIFO depth

This value is in terms of 32-bit words.

Minimum value is 16

Bits 15:0 **PTXSA**: Host periodic TxFIFO start address

The power-on reset value of this register is the sum of the largest Rx data FIFO depth and largest non-periodic Tx data FIFO depth.

**OTG\_FS device IN endpoint transmit FIFO size register (OTG\_FS\_DIEPTXFx)  
(x = 1..3, where x is the FIFO\_number)**

Address offset: 0x104 + (FIFO\_number – 1) × 0x04

Reset value: 0x02000400

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
INEPTXFD																INEPTXSA															
r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	r/r	
w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	w	

Bits 31:16 **INEPTXFD**: IN endpoint TxFIFO depth

This value is in terms of 32-bit words.

Minimum value is 16

The power-on reset value of this register is specified as the largest IN endpoint FIFO number depth.

Bits 15:0 **INEPTXSA**: IN endpoint FIFOx transmit RAM start address

This field contains the memory start address for IN endpoint transmit FIFOx. The address must be aligned with a 32-bit memory location.

### 22.16.3 Host-mode registers

Bit values in the register descriptions are expressed in binary unless otherwise specified.

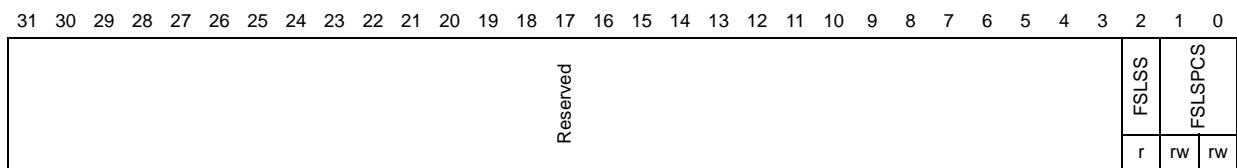
Host-mode registers affect the operation of the core in the host mode. Host mode registers must not be accessed in device mode, as the results are undefined. Host mode registers can be categorized as follows:

#### OTG\_FS Host configuration register (OTG\_FS\_HCFG)

Address offset: 0x400

Reset value: 0x0000 0000

This register configures the core after power-on. Do not make changes to this register after initializing the host.



Bits 31:3 Reserved, must be kept at reset value.

**Bit 2 FSLSS:** FS- and LS-only support

The application uses this bit to control the core's enumeration speed. Using this bit, the application can make the core enumerate as an FS host, even if the connected device supports HS traffic. Do not make changes to this field after initial programming.

1: FS/LS-only, even if the connected device can support HS (read-only)

**Bits 1:0 FSLSPCS:** FS/LS PHY clock select

When the core is in FS host mode

01: PHY clock is running at 48 MHz

Others: Reserved

When the core is in LS host mode

00: Reserved

01: Select 48 MHz PHY clock frequency

10: Select 6 MHz PHY clock frequency

11: Reserved

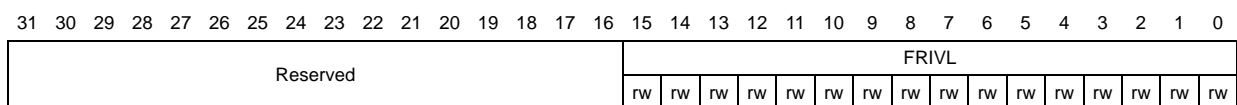
*Note:* The FSLSPCS must be set on a connection event according to the speed of the connected device (after changing this bit, a software reset must be performed).

#### OTG\_FS Host frame interval register (OTG\_FS\_HFIR)

Address offset: 0x404

Reset value: 0x0000 EA60

This register stores the frame interval information for the current speed to which the OTG\_FS controller has enumerated.



Bits 31:16 Reserved, must be kept at reset value.

Bits 15:0 **FRIVL**: Frame interval

The value that the application programs to this field specifies the interval between two consecutive SOFs (FS) or Keep-Alive tokens (LS). This field contains the number of PHY clocks that constitute the required frame interval. The application can write a value to this register only after the Port enable bit of the host port control and status register (PENA bit in OTG\_FS\_HPRT) has been set. If no value is programmed, the core calculates the value based on the PHY clock specified in the FS/LS PHY Clock Select field of the host configuration register (FSLSPCS in OTG\_FS\_HCFG). Do not change the value of this field after the initial configuration.

1 ms x (PHY clock frequency)

### OTG\_FS Host frame number/frame time remaining register (OTG\_FS\_HFNUM)

Address offset: 0x408

Reset value: 0x0000 3FFF

This register indicates the current frame number. It also indicates the time remaining (in terms of the number of PHY clocks) in the current frame.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
FTREM																FRNUM															
r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r

Bits 31:16 **FTREM**: Frame time remaining

Indicates the amount of time remaining in the current frame, in terms of PHY clocks. This field decrements on each PHY clock. When it reaches zero, this field is reloaded with the value in the Frame interval register and a new SOF is transmitted on the USB.

Bits 15:0 **FRNUM**: Frame number

This field increments when a new SOF is transmitted on the USB, and is cleared to 0 when it reaches 0x3FFF.

### OTG\_FS Host periodic transmit FIFO/queue status register (OTG\_FS\_HPTXSTS)

Address offset: 0x410

Reset value: 0x0008 0100

This read-only register contains the free space information for the periodic Tx FIFO and the periodic transmit request queue.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
PTXQTOP								PTXQSAV								PTXFSAVL															
r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r





### OTG\_FS Host all channels interrupt mask register (OTG\_FS\_HAINTMSK)

Address offset: 0x418

Reset value: 0x0000 0000

The host all channel interrupt mask register works with the host all channel interrupt register to interrupt the application when an event occurs on a channel. There is one interrupt mask bit per channel, up to a maximum of 16 bits.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0														
Reserved																HAINTM																													
																rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 31:16 Reserved, must be kept at reset value.

Bits 15:0 **HAINTM**: Channel interrupt mask

0: Masked interrupt

1: Unmasked interrupt

One bit per channel: Bit 0 for channel 0, bit 15 for channel 15

### OTG\_FS Host port control and status register (OTG\_FS\_HPRT)

Address offset: 0x440

Reset value: 0x0000 0000

This register is available only in host mode. Currently, the OTG host supports only one port.

A single register holds USB port-related information such as USB reset, enable, suspend, resume, connect status, and test mode for each port. It is shown in [Figure 250](#). The rc\_w1 bits in this register can trigger an interrupt to the application through the host port interrupt bit of the core interrupt register (HPRTINT bit in OTG\_FS\_GINTSTS). On a Port Interrupt, the application must read this register and clear the bit that caused the interrupt. For the rc\_w1 bits, the application must write a 1 to the bit to clear the interrupt.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
Reserved														PSPD		PTCTL				PPWR	PLSTS		Reserved	PRST	PSUSP	PRES	POCCHNG	POCA	PENCHNG	PENA	PCDET	PCSTS
														r	r	rw	rw	rw	rw	rw	r	r	Reserved	rw	rs	rw	rc_w1	r	rc_w1	rc_w0	rc_w1	r

Bits 31:19 Reserved, must be kept at reset value.

Bits 18:17 **PSPD**: Port speed

Indicates the speed of the device attached to this port.

01: Full speed

10: Low speed

11: Reserved



**Bits 16:13 PTCTL:** Port test control

The application writes a nonzero value to this field to put the port into a Test mode, and the corresponding pattern is signaled on the port.

0000: Test mode disabled  
0001: Test\_J mode  
0010: Test\_K mode  
0011: Test\_SE0\_NAK mode  
0100: Test\_Packet mode  
0101: Test\_Force\_Enable  
Others: Reserved

**Bit 12 PPWR:** Port power

The application uses this field to control power to this port, and the core clears this bit on an overcurrent condition.

0: Power off  
1: Power on

**Bits 11:10 PLSTS:** Port line status

Indicates the current logic level USB data lines

Bit 10: Logic level of OTG\_FS\_FS\_DP  
Bit 11: Logic level of OTG\_FS\_FS\_DM

**Bit 9** Reserved, must be kept at reset value.

**Bit 8 PRST:** Port reset

When the application sets this bit, a reset sequence is started on this port. The application must time the reset period and clear this bit after the reset sequence is complete.

0: Port not in reset  
1: Port in reset

The application must leave this bit set for a minimum duration of at least 10 ms to start a reset on the port. The application can leave it set for another 10 ms in addition to the required minimum duration, before clearing the bit, even though there is no maximum limit set by the USB standard.

**Bit 7 PSUSP:** Port suspend

The application sets this bit to put this port in Suspend mode. The core only stops sending SOFs when this is set. To stop the PHY clock, the application must set the Port clock stop bit, which asserts the suspend input pin of the PHY.

The read value of this bit reflects the current suspend status of the port. This bit is cleared by the core after a remote wakeup signal is detected or the application sets the Port reset bit or Port resume bit in this register or the Resume/remote wakeup detected interrupt bit or Disconnect detected interrupt bit in the Core interrupt register (WKUINT or DISCINT in OTG\_FS\_GINTSTS, respectively).

0: Port not in Suspend mode  
1: Port in Suspend mode

**Bit 6 PRES:** Port resume

The application sets this bit to drive resume signaling on the port. The core continues to drive the resume signal until the application clears this bit.

If the core detects a USB remote wakeup sequence, as indicated by the Port resume/remote wakeup detected interrupt bit of the Core interrupt register (WKUINT bit in OTG\_FS\_GINTSTS), the core starts driving resume signaling without application intervention and clears this bit when it detects a disconnect condition. The read value of this bit indicates whether the core is currently driving resume signaling.

0: No resume driven  
1: Resume driven

- Bit 5 **POCCHNG**: Port overcurrent change  
The core sets this bit when the status of the Port overcurrent active bit (bit 4) in this register changes.
- Bit 4 **POCA**: Port overcurrent active  
Indicates the overcurrent condition of the port.  
0: No overcurrent condition  
1: Overcurrent condition
- Bit 3 **PENCHNG**: Port enable/disable change  
The core sets this bit when the status of the Port enable bit 2 in this register changes.
- Bit 2 **PENA**: Port enable  
A port is enabled only by the core after a reset sequence, and is disabled by an overcurrent condition, a disconnect condition, or by the application clearing this bit. The application cannot set this bit by a register write. It can only clear it to disable the port. This bit does not trigger any interrupt to the application.  
0: Port disabled  
1: Port enabled
- Bit 1 **PCDET**: Port connect detected  
The core sets this bit when a device connection is detected to trigger an interrupt to the application using the host port interrupt bit in the Core interrupt register (HPRTINT bit in OTG\_FS\_GINTSTS). The application must write a 1 to this bit to clear the interrupt.
- Bit 0 **PCSTS**: Port connect status  
0: No device is attached to the port  
1: A device is attached to the port

**OTG\_FS Host channel-x characteristics register (OTG\_FS\_HCCHARx)  
(x = 0..7, where x = Channel\_number)**

Address offset: 0x500 + (Channel\_number × 0x20)

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
CHENA	CHDIS	ODDFRM	DAD						MCNT		EPTYP		LSDEV	Reserved	EPDIR	EPNUM				MPSIZ												
rs	rs	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

- Bit 31 CHENA:** Channel enable  
 This field is set by the application and cleared by the OTG host.  
 0: Channel disabled  
 1: Channel enabled
- Bit 30 CHDIS:** Channel disable  
 The application sets this bit to stop transmitting/receiving data on a channel, even before the transfer for that channel is complete. The application must wait for the Channel disabled interrupt before treating the channel as disabled.
- Bit 29 ODDFRM:** Odd frame  
 This field is set (reset) by the application to indicate that the OTG host must perform a transfer in an odd frame. This field is applicable for only periodic (isochronous and interrupt) transactions.  
 0: Even frame  
 1: Odd frame
- Bits 28:22 DAD:** Device address  
 This field selects the specific device serving as the data source or sink.
- Bits 21:20 MCNT:** Multicount  
 This field indicates to the host the number of transactions that must be executed per frame for this periodic endpoint. For non-periodic transfers, this field is not used  
 00: Reserved. This field yields undefined results  
 01: 1 transaction  
 10: 2 transactions per frame to be issued for this endpoint  
 11: 3 transactions per frame to be issued for this endpoint  
*Note: This field must be set to at least 01.*
- Bits 19:18 EPTYP:** Endpoint type  
 Indicates the transfer type selected.  
 00: Control  
 01: Isochronous  
 10: Bulk  
 11: Interrupt
- Bit 17 LSDEV:** Low-speed device  
 This field is set by the application to indicate that this channel is communicating to a low-speed device.
- Bit 16** Reserved, must be kept at reset value.



Bit 15 **EPDIR**: Endpoint direction  
 Indicates whether the transaction is IN or OUT.  
 0: OUT  
 1: IN

Bits 14:11 **EPNUM**: Endpoint number  
 Indicates the endpoint number on the device serving as the data source or sink.

Bits 10:0 **MPSIZ**: Maximum packet size  
 Indicates the maximum packet size of the associated endpoint.

**OTG\_FS Host channel-x interrupt register (OTG\_FS\_HCINTx) (x = 0..7, where x = Channel\_number)**

Address offset: 0x508 + (Channel\_number × 0x20)

Reset value: 0x0000 0000

This register indicates the status of a channel with respect to USB- and AHB-related events. It is shown in *Figure 250*. The application must read this register when the host channels interrupt bit in the Core interrupt register (HCINT bit in OTG\_FS\_GINTSTS) is set. Before the application can read this register, it must first read the host all channels interrupt (OTG\_FS\_HAINT) register to get the exact channel number for the host channel-x interrupt register. The application must clear the appropriate bit in this register to clear the corresponding bits in the OTG\_FS\_HAINT and OTG\_FS\_GINTSTS registers.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
Reserved																						DTERR	FRMOR	BBERR	TXERR	Reserved	ACK	NAK	STALL	Reserved	CHH	XFRC
																						rc_w1	rc_w1	rc_w1	rc_w1		rc_w1	rc_w1	rc_w1		rc_w1	rc_w1

Bits 31:11 Reserved, must be kept at reset value.

Bit 10 **DTERR**: Data toggle error

Bit 9 **FRMOR**: Frame overrun

Bit 8 **BBERR**: Babble error

Bit 7 **TXERR**: Transaction error

Indicates one of the following errors occurred on the USB.  
 CRC check failure  
 Timeout  
 Bit stuff error  
 False EOP

Bit 6 Reserved, must be kept at reset value.

Bit 5 **ACK**: ACK response received/transmitted interrupt

Bit 4 **NAK**: NAK response received interrupt

Bit 3 **STALL**: STALL response received interrupt

Bit 2 Reserved, must be kept at reset value.

Bit 1 **CHH**: Channel halted

Indicates the transfer completed abnormally either because of any USB transaction error or in response to disable request by the application.

Bit 0 **XFRC**: Transfer completed

Transfer completed normally without any errors.

**OTG\_FS Host channel-x interrupt mask register (OTG\_FS\_HCINTMSKx)  
(x = 0..7, where x = Channel\_number)**

Address offset: 0x50C + (Channel\_number × 0x20)

Reset value: 0x0000 0000

This register reflects the mask for each channel status described in the previous section.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved																					DTERRM	FRMORM	BBERRM	TXERRM	NYET	ACKM	NAKM	STALLM	Reserved	CHHM	XFRCM
																					rw	rw	rw	rw	rw	rw	rw	rw		rw	rw

Bits 31:11 Reserved, must be kept at reset value.

Bit 10 **DTERRM**: Data toggle error mask

0: Masked interrupt  
1: Unmasked interrupt

Bit 9 **FRMORM**: Frame overrun mask

0: Masked interrupt  
1: Unmasked interrupt

Bit 8 **BBERRM**: Babble error mask

0: Masked interrupt  
1: Unmasked interrupt

Bit 7 **TXERRM**: Transaction error mask

0: Masked interrupt  
1: Unmasked interrupt

Bit 6 **NYET**: response received interrupt mask

0: Masked interrupt  
1: Unmasked interrupt

Bit 5 **ACKM**: ACK response received/transmitted interrupt mask

0: Masked interrupt  
1: Unmasked interrupt

Bit 4 **NAKM**: NAK response received interrupt mask

0: Masked interrupt  
1: Unmasked interrupt

Bit 3 **STALLM**: STALL response received interrupt mask

0: Masked interrupt  
1: Unmasked interrupt

Bit 2 Reserved, must be kept at reset value.

Bit 1 **CHHM**: Channel halted mask  
 0: Masked interrupt  
 1: Unmasked interrupt

Bit 0 **XFRM**: Transfer completed mask  
 0: Masked interrupt  
 1: Unmasked interrupt

**OTG\_FS Host channel-x transfer size register (OTG\_FS\_HCTSIZx) (x = 0..7, where x = Channel\_number)**

Address offset: 0x510 + (Channel\_number × 0x20)

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved	DPID			PKTCNT									XFRSIZ																		
	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bit 31 Reserved, must be kept at reset value.

Bits 30:29 **DPID**: Data PID

The application programs this field with the type of PID to use for the initial transaction. The host maintains this field for the rest of the transfer.  
 00: DATA0  
 01: DATA2  
 10: DATA1  
 11: MDATA (non-control)/SETUP (control)

Bits 28:19 **PKTCNT**: Packet count

This field is programmed by the application with the expected number of packets to be transmitted (OUT) or received (IN).  
 The host decrements this count on every successful transmission or reception of an OUT/IN packet. Once this count reaches zero, the application is interrupted to indicate normal completion.

Bits 18:0 **XFRSIZ**: Transfer size

For an OUT, this field is the number of data bytes the host sends during the transfer.  
 For an IN, this field is the buffer size that the application has reserved for the transfer. The application is expected to program this field as an integer multiple of the maximum packet size for IN transactions (periodic and non-periodic).



### 22.16.4 Device-mode registers

#### OTG\_FS device configuration register (OTG\_FS\_DCFG)

Address offset: 0x800

Reset value: 0x0220 0000

This register configures the core in device mode after power-on or after certain control commands or enumeration. Do not make changes to this register after initial programming.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0																
Reserved																			PFIVL	DAD							Reserved	NZLSOHSK		DSPD																	
																			rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bits 31:13 **Reserved**, must be kept at reset value.

Bits 12:11 **PFIVL**: Periodic frame interval

Indicates the time within a frame at which the application must be notified using the end of periodic frame interrupt. This can be used to determine if all the isochronous traffic for that frame is complete.

- 00: 80% of the frame interval
- 01: 85% of the frame interval
- 10: 90% of the frame interval
- 11: 95% of the frame interval

Bits 10:4 **DAD**: Device address

The application must program this field after every SetAddress control command.

Bit 3 **Reserved**, must be kept at reset value.

Bit 2 **NZLSOHSK**: Non-zero-length status OUT handshake

The application can use this field to select the handshake the core sends on receiving a nonzero-length data packet during the OUT transaction of a control transfer's Status stage.

- 1: Send a STALL handshake on a nonzero-length status OUT transaction and do not send the received OUT packet to the application.
- 0: Send the received OUT packet to the application (zero-length or nonzero-length) and send a handshake based on the NAK and STALL bits for the endpoint in the Device endpoint control register.

Bits 1:0 **DSPD**: Device speed

Indicates the speed at which the application requires the core to enumerate, or the maximum speed the application can support. However, the actual bus speed is determined only after the chirp sequence is completed, and is based on the speed of the USB host to which the core is connected.

- 00: Reserved
- 01: Reserved
- 10: Reserved
- 11: Full speed (USB 1.1 transceiver clock is 48 MHz)

**OTG\_FS device control register (OTG\_FS\_DCTL)**

Address offset: 0x804

Reset value: 0x0000 0000

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved																				POPRGDNE	CGONAK	SGONAK	CGINAK	SGINAK	TCTL			GONSTS	GINSTS	SDIS	RWUSIG
																				rw	w	w	w	w	rw	rw	rw	r	r	rw	rw

Bits 31:12 Reserved, must be kept at reset value.

Bit 11 **POPRGDNE**: Power-on programming done

The application uses this bit to indicate that register programming is completed after a wakeup from power down mode.

Bit 10 **CGONAK**: Clear global OUT NAK

A write to this field clears the Global OUT NAK.

Bit 9 **SGONAK**: Set global OUT NAK

A write to this field sets the Global OUT NAK.

The application uses this bit to send a NAK handshake on all OUT endpoints.

The application must set this bit only after making sure that the Global OUT NAK

effective bit in the Core interrupt register (GONAKEFF bit in OTG\_FS\_GINTSTS) is cleared.

Bit 8 **CGINAK**: Clear global IN NAK

A write to this field clears the Global IN NAK.

Bit 7 **SGINAK**: Set global IN NAK

A write to this field sets the Global non-periodic IN NAK. The application uses this bit to send a NAK handshake on all non-periodic IN endpoints.

The application must set this bit only after making sure that the Global IN NAK effective bit in the Core interrupt register (GINAKEFF bit in OTG\_FS\_GINTSTS) is cleared.

Bits 6:4 **TCTL**: Test control

000: Test mode disabled

001: Test\_J mode

010: Test\_K mode

011: Test\_SE0\_NAK mode

100: Test\_Packet mode

101: Test\_Force\_Enable

Others: Reserved

Bit 3 **GONSTS**: Global OUT NAK status

0: A handshake is sent based on the FIFO Status and the NAK and STALL bit settings.

1: No data is written to the Rx FIFO, irrespective of space availability. Sends a NAK handshake on all packets, except on SETUP transactions. All isochronous OUT packets are dropped.



Bit 3 **EERR**: Erratic error

The core sets this bit to report any erratic errors.  
 Due to erratic errors, the OTG\_FS controller goes into Suspended state and an interrupt is generated to the application with Early suspend bit of the OTG\_FS\_GINTSTS register (ESUSP bit in OTG\_FS\_GINTSTS). If the early suspend is asserted due to an erratic error, the application can only perform a soft disconnect recover.

Bits 2:1 **ENUMSPD**: Enumerated speed

Indicates the speed at which the OTG\_FS controller has come up after speed detection through a chirp sequence.

- 01: Reserved
- 10: Reserved
- 11: Full speed (PHY clock is running at 48 MHz)
- Others: reserved

Bit 0 **SUSPSTS**: Suspend status

In device mode, this bit is set as long as a Suspend condition is detected on the USB. The core enters the Suspended state when there is no activity on the USB data lines for a period of 3 ms. The core comes out of the suspend:

- When there is an activity on the USB data lines
- When the application writes to the Remote wakeup signaling bit in the OTG\_FS\_DCTL register (RWUSIG bit in OTG\_FS\_DCTL).

**OTG\_FS device IN endpoint common interrupt mask register (OTG\_FS\_DIEPMSK)**

Address offset: 0x810

Reset value: 0x0000 0000

This register works with each of the OTG\_FS\_DIEPINTx registers for all endpoints to generate an interrupt per IN endpoint. The IN endpoint interrupt for a specific status in the OTG\_FS\_DIEPINTx register can be masked by writing to the corresponding bit in this register. Status bits are masked by default.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved																								INEPNEM	INEPNMM	ITTXFEMSK	TOM	Reserved	EPDM	XFRM	
																								rw	rw	rw	rw		rw	rw	

Bits 31:7 Reserved, must be kept at reset value.

Bit 6 **INEPNEM**: IN endpoint NAK effective mask

- 0: Masked interrupt
- 1: Unmasked interrupt

Bit 5 **INEPNMM**: IN token received with EP mismatch mask

- 0: Masked interrupt
- 1: Unmasked interrupt

Bit 4 **ITTXFEMSK**: IN token received when Tx FIFO empty mask

- 0: Masked interrupt
- 1: Unmasked interrupt





### OTG\_FS device all endpoints interrupt register (OTG\_FS\_DAINTR)

Address offset: 0x818

Reset value: 0x0000 0000

When a significant event occurs on an endpoint, a OTG\_FS\_DAINTR register interrupts the application using the Device OUT endpoints interrupt bit or Device IN endpoints interrupt bit of the OTG\_FS\_GINTSTS register (OEPINT or IEPINT in OTG\_FS\_GINTSTS, respectively). There is one interrupt bit per endpoint, up to a maximum of 16 bits for OUT endpoints and 16 bits for IN endpoints. For a bidirectional endpoint, the corresponding IN and OUT interrupt bits are used. Bits in this register are set and cleared when the application sets and clears bits in the corresponding Device Endpoint-x interrupt register (OTG\_FS\_DIEPINTx/OTG\_FS\_DOEPINTx).

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
OEPINT																IEPINT															
r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r	r

Bits 31:16 **OEPINT**: OUT endpoint interrupt bits  
 One bit per OUT endpoint:  
 Bit 16 for OUT endpoint 0, bit 18 for OUT endpoint 3.

Bits 15:0 **IEPINT**: IN endpoint interrupt bits  
 One bit per IN endpoint:  
 Bit 0 for IN endpoint 0, bit 3 for endpoint 3.

### OTG\_FS all endpoints interrupt mask register (OTG\_FS\_DAINTRMSK)

Address offset: 0x81C

Reset value: 0x0000 0000

The OTG\_FS\_DAINTRMSK register works with the Device endpoint interrupt register to interrupt the application when an event occurs on a device endpoint. However, the OTG\_FS\_DAINTR register bit corresponding to that interrupt is still set.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
OEPM																IEPM															
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	

Bits 31:16 **OEPM**: OUT EP interrupt mask bits  
 One per OUT endpoint:  
 Bit 16 for OUT EP 0, bit 18 for OUT EP 3  
 0: Masked interrupt  
 1: Unmasked interrupt

Bits 15:0 **IEPM**: IN EP interrupt mask bits  
 One bit per IN endpoint:  
 Bit 0 for IN EP 0, bit 3 for IN EP 3  
 0: Masked interrupt  
 1: Unmasked interrupt

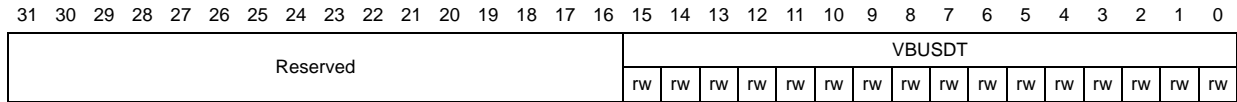


**OTG\_FS device V<sub>BUS</sub> discharge time register (OTG\_FS\_DVBUSDIS)**

Address offset: 0x0828

Reset value: 0x0000 17D7

This register specifies the V<sub>BUS</sub> discharge time after V<sub>BUS</sub> pulsing during SRP.



Bits 31:16 Reserved, must be kept at reset value.

Bits 15:0 **VBUSDT**: Device V<sub>BUS</sub> discharge time

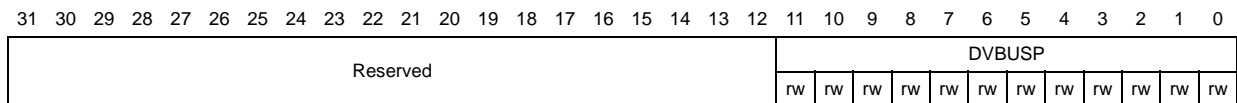
Specifies the V<sub>BUS</sub> discharge time after V<sub>BUS</sub> pulsing during SRP. This value equals:  
 V<sub>BUS</sub> discharge time in PHY clocks / 1 024  
 Depending on your V<sub>BUS</sub> load, this value may need adjusting.

**OTG\_FS device V<sub>BUS</sub> pulsing time register (OTG\_FS\_DVBUSPULSE)**

Address offset: 0x082C

Reset value: 0x0000 05B8

This register specifies the V<sub>BUS</sub> pulsing time during SRP.



Bits 31:12 Reserved, must be kept at reset value.

Bits 11:0 **DVBUSP**: Device V<sub>BUS</sub> pulsing time

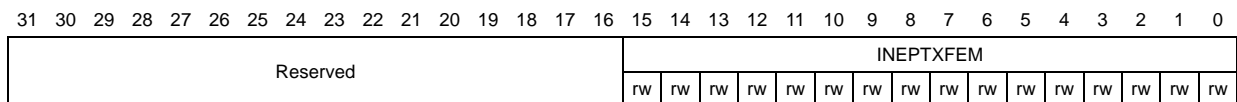
Specifies the V<sub>BUS</sub> pulsing time during SRP. This value equals:  
 V<sub>BUS</sub> pulsing time in PHY clocks / 1 024

**OTG\_FS device IN endpoint FIFO empty interrupt mask register:  
 (OTG\_FS\_DIEPEMPMSK)**

Address offset: 0x834

Reset value: 0x0000 0000

This register is used to control the IN endpoint FIFO empty interrupt generation (TXFE\_OTG\_FS\_DIEPINTx).



Bits 31:16 Reserved, must be kept at reset value.

Bits 15:0 **INEPTXFEM**: IN EP Tx FIFO empty interrupt mask bits

These bits act as mask bits for OTG\_FS\_DIEPINTx.

TXFE interrupt one bit per IN endpoint:

Bit 0 for IN endpoint 0, bit 3 for IN endpoint 3

0: Masked interrupt

1: Unmasked interrupt

### OTG\_FS device control IN endpoint 0 control register (OTG\_FS\_DIEPCTL0)

Address offset: 0x900

Reset value: 0x0000 0000

This section describes the OTG\_FS\_DIEPCTL0 register. Nonzero control endpoints use registers for endpoints 1–3.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0		
EPENA	EPDIS	Reserved		SNAK	CNAK	TXFNUM				STALL	Reserved	EPTYP		NAKSTS	Reserved	USBAEP	Reserved										MPSIZ						
r	r			w	w	rw	rw	rw	rw	rs		r	r	r		r																rw	rw

Bit 31 **EPENA**: Endpoint enable

The application sets this bit to start transmitting data on the endpoint 0.

The core clears this bit before setting any of the following interrupts on this endpoint:

- Endpoint disabled
- Transfer completed

Bit 30 **EPDIS**: Endpoint disable

The application sets this bit to stop transmitting data on an endpoint, even before the transfer for that endpoint is complete. The application must wait for the Endpoint disabled interrupt before treating the endpoint as disabled. The core clears this bit before setting the Endpoint disabled interrupt. The application must set this bit only if Endpoint enable is already set for this endpoint.

Bits 29:28 Reserved, must be kept at reset value.

Bit 27 **SNAK**: Set NAK

A write to this bit sets the NAK bit for the endpoint.

Using this bit, the application can control the transmission of NAK handshakes on an endpoint. The core can also set this bit for an endpoint after a SETUP packet is received on that endpoint.

Bit 26 **CNAK**: Clear NAK

**A write to this bit clears the NAK bit for the endpoint.**

Bits 25:22 **TXFNUM**: TxFIFO number

This value is set to the FIFO number that is assigned to IN endpoint 0.

Bit 21 **STALL**: STALL handshake

The application can only set this bit, and the core clears it when a SETUP token is received for this endpoint. If a NAK bit, a Global IN NAK or Global OUT NAK is set along with this bit, the STALL bit takes priority.



Bit 20 Reserved, must be kept at reset value.

Bits 19:18 **EPTYP**: Endpoint type  
 Hardcoded to '00' for control.

Bit 17 **NAKSTS**: NAK status  
 Indicates the following:  
 0: The core is transmitting non-NAK handshakes based on the FIFO status  
 1: The core is transmitting NAK handshakes on this endpoint.  
 When this bit is set, either by the application or core, the core stops transmitting data, even if there are data available in the TxFIFO. Irrespective of this bit's setting, the core always responds to SETUP data packets with an ACK handshake.

Bit 16 Reserved, must be kept at reset value.

Bit 15 **USBAEP**: USB active endpoint  
 This bit is always set to 1, indicating that control endpoint 0 is always active in all configurations and interfaces.

Bits 14:2 Reserved, must be kept at reset value.

Bits 1:0 **MPSIZ**: Maximum packet size  
 The application must program this field with the maximum packet size for the current logical endpoint.  
 00: 64 bytes  
 01: 32 bytes  
 10: 16 bytes  
 11: 8 bytes

**OTG device endpoint-x control register (OTG\_FS\_DIEPCTLx) (x = 1..3, where x = Endpoint\_number)**

Address offset: 0x900 + (Endpoint\_number × 0x20)

Reset value: 0x0000 0000

The application uses this register to control the behavior of each logical endpoint other than endpoint 0.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
EPENA	EPDIS	SODDFRM	SD0PID/SEV/NFRM	SNAK	CNAK	TXFNUM				Stall	Reserved	EPTYP	NAKSTS	EONUM/DPID	USBAEP	Reserved					MPSIZ										
rs	rs	w	w	w	w	rw	rw	rw	rw	rw/rs		rw	rw	r	r	rw						rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bit 31 **EPENA**: Endpoint enable  
 The application sets this bit to start transmitting data on an endpoint.  
 The core clears this bit before setting any of the following interrupts on this endpoint:

- SETUP phase done
- Endpoint disabled
- Transfer completed



- Bit 30 **EPDIS**: Endpoint disable  
The application sets this bit to stop transmitting/receiving data on an endpoint, even before the transfer for that endpoint is complete. The application must wait for the Endpoint disabled interrupt before treating the endpoint as disabled. The core clears this bit before setting the Endpoint disabled interrupt. The application must set this bit only if Endpoint enable is already set for this endpoint.
- Bit 29 **SODDFRM**: Set odd frame  
Applies to isochronous IN and OUT endpoints only.  
Writing to this field sets the Even/Odd frame (EONUM) field to odd frame.
- Bit 28 **SD0PID**: Set DATA0 PID  
Applies to interrupt/bulk IN endpoints only.  
Writing to this field sets the endpoint data PID (DPID) field in this register to DATA0.
- SEVNFRM**: Set even frame  
Applies to isochronous IN endpoints only.  
Writing to this field sets the Even/Odd frame (EONUM) field to even frame.
- Bit 27 **SNAK**: Set NAK  
A write to this bit sets the NAK bit for the endpoint.  
Using this bit, the application can control the transmission of NAK handshakes on an endpoint. The core can also set this bit for OUT endpoints on a Transfer completed interrupt, or after a SETUP is received on the endpoint.
- Bit 26 **CNAK**: Clear NAK  
A write to this bit clears the NAK bit for the endpoint.
- Bits 25:22 **TXFNUM**: TxFIFO number  
These bits specify the FIFO number associated with this endpoint. Each active IN endpoint must be programmed to a separate FIFO number.  
This field is valid only for IN endpoints.
- Bit 21 **STALL**: STALL handshake  
Applies to non-control, non-isochronous IN endpoints only (access type is rw).  
The application sets this bit to stall all tokens from the USB host to this endpoint. If a NAK bit, Global IN NAK, or Global OUT NAK is set along with this bit, the STALL bit takes priority.  
Only the application can clear this bit, never the core.  
  
Applies to control endpoints only (access type is rs).  
The application can only set this bit, and the core clears it, when a SETUP token is received for this endpoint. If a NAK bit, Global IN NAK, or Global OUT NAK is set along with this bit, the STALL bit takes priority. Irrespective of this bit's setting, the core always responds to SETUP data packets with an ACK handshake.
- Bit 20 Reserved, must be kept at reset value.
- Bits 19:18 **EPTYP**: Endpoint type  
This is the transfer type supported by this logical endpoint.  
00: Control  
01: Isochronous  
10: Bulk  
11: Interrupt

**Bit 17 NAKSTS:** NAK status

It indicates the following:

0: The core is transmitting non-NAK handshakes based on the FIFO status.

1: The core is transmitting NAK handshakes on this endpoint.

When either the application or the core sets this bit:

For non-isochronous IN endpoints: The core stops transmitting any data on an IN endpoint, even if there are data available in the TxFIFO.

For isochronous IN endpoints: The core sends out a zero-length data packet, even if there are data available in the TxFIFO.

Irrespective of this bit's setting, the core always responds to SETUP data packets with an ACK handshake.

**Bit 16 EONUM:** Even/odd frame

Applies to isochronous IN endpoints only.

Indicates the frame number in which the core transmits/receives isochronous data for this endpoint. The application must program the even/odd frame number in which it intends to transmit/receive isochronous data for this endpoint using the SEVNFRM and SODDFRM fields in this register.

0: Even frame

1: Odd frame

**DPID:** Endpoint data PID

Applies to interrupt/bulk IN endpoints only.

Contains the PID of the packet to be received or transmitted on this endpoint. The application must program the PID of the first packet to be received or transmitted on this endpoint, after the endpoint is activated. The application uses the SDOPID register field to program either DATA0 or DATA1 PID.

0: DATA0

1: DATA1

**Bit 15 USBAEP:** USB active endpoint

Indicates whether this endpoint is active in the current configuration and interface. The core clears this bit for all endpoints (other than EP 0) after detecting a USB reset. After receiving the SetConfiguration and SetInterface commands, the application must program endpoint registers accordingly and set this bit.

Bits 14:11 Reserved, must be kept at reset value.

**Bits 10:0 MPSIZ:** Maximum packet size

The application must program this field with the maximum packet size for the current logical endpoint. This value is in bytes.

**OTG\_FS device control OUT endpoint 0 control register (OTG\_FS\_DOEPCTL0)**

Address offset: 0xB00

Reset value: 0x0000 8000

This section describes the OTG\_FS\_DOEPCTL0 register. Nonzero control endpoints use registers for endpoints 1–3.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
EPENA	EPDIS	Reserved		SNAK	CNAK	Reserved					Stall	SNPM	EPTYP		NAKSTS	Reserved	USBAEP	Reserved										MPSIZ			
w	r			w	w						rs	rw	r	r	r		r											r	r		

Bit 31 **EPENA**: Endpoint enable

The application sets this bit to start transmitting data on endpoint 0.

The core clears this bit before setting any of the following interrupts on this endpoint:

- SETUP phase done
- Endpoint disabled
- Transfer completed

Bit 30 **EPDIS**: Endpoint disable

The application cannot disable control OUT endpoint 0.

Bits 29:28 Reserved, must be kept at reset value.

Bit 27 **SNAK**: Set NAK

A write to this bit sets the NAK bit for the endpoint.

Using this bit, the application can control the transmission of NAK handshakes on an endpoint. The core can also set this bit on a Transfer completed interrupt, or after a SETUP is received on the endpoint.

Bit 26 **CNAK**: Clear NAK

A write to this bit clears the NAK bit for the endpoint.

Bits 25:22 Reserved, must be kept at reset value.

Bit 21 **STALL**: STALL handshake

The application can only set this bit, and the core clears it, when a SETUP token is received for this endpoint. If a NAK bit or Global OUT NAK is set along with this bit, the STALL bit takes priority. Irrespective of this bit's setting, the core always responds to SETUP data packets with an ACK handshake.

Bit 20 **SNPM**: Snoop mode

This bit configures the endpoint to Snoop mode. In Snoop mode, the core does not check the correctness of OUT packets before transferring them to application memory.

Bits 19:18 **EPTYP**: Endpoint type

Hardcoded to 2'b00 for control.

Bit 17 **NAKSTS**: NAK status

Indicates the following:

0: The core is transmitting non-NAK handshakes based on the FIFO status.

1: The core is transmitting NAK handshakes on this endpoint.

When either the application or the core sets this bit, the core stops receiving data, even if there is space in the RxFIFO to accommodate the incoming packet. Irrespective of this bit's setting, the core always responds to SETUP data packets with an ACK handshake.

Bit 16 Reserved, must be kept at reset value.

Bit 15 **USBAEP**: USB active endpoint

This bit is always set to 1, indicating that a control endpoint 0 is always active in all configurations and interfaces.

Bits 14:2 Reserved, must be kept at reset value.

Bits 1:0 **MPSIZ**: Maximum packet size

The maximum packet size for control OUT endpoint 0 is the same as what is programmed in control IN endpoint 0.

00: 64 bytes

01: 32 bytes

10: 16 bytes

11: 8 bytes

**OTG\_FS device endpoint-x control register (OTG\_FS\_DOEPCCTLx) (x = 1..3, where x = Endpoint\_number)**

Address offset for OUT endpoints: 0xB00 + (Endpoint\_number × 0x20)

Reset value: 0x0000 0000

The application uses this register to control the behavior of each logical endpoint other than endpoint 0.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0			
EPENA	EPDIS	SODDFRM/SD1PID	SD0PID/SEVNFRM	SNAK	CNAK	Reserved					Stall	SNPM	EPTYP		NAKSTS	EONUM/DPID	USBAEP	Reserved					MPSIZ											
rs	rs	w	w	w	w						rw/rs	rw	rw	rw	r	r	rw						rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Bit 31 **EPENA**: Endpoint enable

Applies to IN and OUT endpoints.

The application sets this bit to start transmitting data on an endpoint.

The core clears this bit before setting any of the following interrupts on this endpoint:

- SETUP phase done
- Endpoint disabled
- Transfer completed



- Bit 30 **EPDIS**: Endpoint disable  
The application sets this bit to stop transmitting/receiving data on an endpoint, even before the transfer for that endpoint is complete. The application must wait for the Endpoint disabled interrupt before treating the endpoint as disabled. The core clears this bit before setting the Endpoint disabled interrupt. The application must set this bit only if Endpoint enable is already set for this endpoint.
- Bit 29 **SD1PID**: Set DATA1 PID  
Applies to interrupt/bulk IN and OUT endpoints only. Writing to this field sets the endpoint data PID (DPID) field in this register to DATA1.  
**SODDFRM**: Set odd frame  
Applies to isochronous IN and OUT endpoints only. Writing to this field sets the Even/Odd frame (EONUM) field to odd frame.
- Bit 28 **SD0PID**: Set DATA0 PID  
Applies to interrupt/bulk OUT endpoints only.  
Writing to this field sets the endpoint data PID (DPID) field in this register to DATA0.  
**SEVNFRM**: Set even frame  
Applies to isochronous OUT endpoints only.  
Writing to this field sets the Even/Odd frame (EONUM) field to even frame.
- Bit 27 **SNAK**: Set NAK  
A write to this bit sets the NAK bit for the endpoint.  
Using this bit, the application can control the transmission of NAK handshakes on an endpoint. The core can also set this bit for OUT endpoints on a Transfer Completed interrupt, or after a SETUP is received on the endpoint.
- Bit 26 **CNAK**: Clear NAK  
A write to this bit clears the NAK bit for the endpoint.
- Bits 25:22 Reserved, must be kept at reset value.
- Bit 21 **STALL**: STALL handshake  
Applies to non-control, non-isochronous OUT endpoints only (access type is rw).  
The application sets this bit to stall all tokens from the USB host to this endpoint. If a NAK bit, Global IN NAK, or Global OUT NAK is set along with this bit, the STALL bit takes priority. Only the application can clear this bit, never the core.  
  
Applies to control endpoints only (access type is rs).  
The application can only set this bit, and the core clears it, when a SETUP token is received for this endpoint. If a NAK bit, Global IN NAK, or Global OUT NAK is set along with this bit, the STALL bit takes priority. Irrespective of this bit's setting, the core always responds to SETUP data packets with an ACK handshake.
- Bit 20 **SNPM**: Snoop mode  
This bit configures the endpoint to Snoop mode. In Snoop mode, the core does not check the correctness of OUT packets before transferring them to application memory.
- Bits 19:18 **EPTYP**: Endpoint type  
This is the transfer type supported by this logical endpoint.  
00: Control  
01: Isochronous  
10: Bulk  
11: Interrupt

**Bit 17 NAKSTS:** NAK status

Indicates the following:

0: The core is transmitting non-NAK handshakes based on the FIFO status.

1: The core is transmitting NAK handshakes on this endpoint.

When either the application or the core sets this bit:

The core stops receiving any data on an OUT endpoint, even if there is space in the RxFIFO to accommodate the incoming packet.

Irrespective of this bit's setting, the core always responds to SETUP data packets with an ACK handshake.

**Bit 16 EONUM:** Even/odd frame

Applies to isochronous IN and OUT endpoints only.

Indicates the frame number in which the core transmits/receives isochronous data for this endpoint. The application must program the even/odd frame number in which it intends to transmit/receive isochronous data for this endpoint using the SEVNFRM and SODDFRM fields in this register.

0: Even frame

1: Odd frame

**DPID:** Endpoint data PID

Applies to interrupt/bulk OUT endpoints only.

Contains the PID of the packet to be received or transmitted on this endpoint. The application must program the PID of the first packet to be received or transmitted on this endpoint, after the endpoint is activated. The application uses the SDOPID register field to program either DATA0 or DATA1 PID.

0: DATA0

1: DATA1

**Bit 15 USBAEP:** USB active endpoint

Indicates whether this endpoint is active in the current configuration and interface. The core clears this bit for all endpoints (other than EP 0) after detecting a USB reset. After receiving the SetConfiguration and SetInterface commands, the application must program endpoint registers accordingly and set this bit.

Bits 14:11 Reserved, must be kept at reset value.

**Bits 10:0 MPSIZ:** Maximum packet size

The application must program this field with the maximum packet size for the current logical endpoint. This value is in bytes.

**OTG\_FS device endpoint-x interrupt register (OTG\_FS\_DIEPINTx) (x = 0..3, where x = Endpoint\_number)**

Address offset: 0x908 + (Endpoint\_number × 0x20)

Reset value: 0x0000 0080

This register indicates the status of an endpoint with respect to USB- and AHB-related events. It is shown in *Figure 250*. The application must read this register when the IN endpoints interrupt bit of the Core interrupt register (IEPINT in OTG\_FS\_GINTSTS) is set. Before the application can read this register, it must first read the device all endpoints interrupt (OTG\_FS\_DAINTE) register to get the exact endpoint number for the Device endpoint-x interrupt register. The application must clear the appropriate bit in this register to clear the corresponding bits in the OTG\_FS\_DAINTE and OTG\_FS\_GINTSTS registers.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved																								TXFE	INEPNE	Reserved	ITTXFE	TOC	Reserved	EPDISD	XFRC
																								r	rc_w1/rw	Reserved	rc_w1	rc_w1	Reserved	rc_w1	rc_w1

Bits 31:8 Reserved, must be kept at reset value.

Bit 7 **TXFE**: Transmit FIFO empty

This interrupt is asserted when the Tx FIFO for this endpoint is either half or completely empty. The half or completely empty status is determined by the Tx FIFO Empty Level bit in the OTG\_FS\_GAHBCFG register (TXFELVL bit in OTG\_FS\_GAHBCFG).

Bit 6 **INEPNE**: IN endpoint NAK effective

This bit can be cleared when the application clears the IN endpoint NAK by writing to the CNAK bit in OTG\_FS\_DIEPCTLx.

This interrupt indicates that the core has sampled the NAK bit set (either by the application or by the core). The interrupt indicates that the IN endpoint NAK bit set by the application has taken effect in the core.

This interrupt does not guarantee that a NAK handshake is sent on the USB. A STALL bit takes priority over a NAK bit.

Bit 5 Reserved, must be kept at reset value.

Bit 4 **ITTXFE**: IN token received when Tx FIFO is empty

Applies to non-periodic IN endpoints only.

Indicates that an IN token was received when the associated Tx FIFO (periodic/non-periodic) was empty. This interrupt is asserted on the endpoint for which the IN token was received.

Bit 3 **TOC**: Timeout condition

Applies only to Control IN endpoints.

Indicates that the core has detected a timeout condition on the USB for the last IN token on this endpoint.

Bit 2 Reserved, must be kept at reset value.

Bit 1 **EPDISD**: Endpoint disabled interrupt

This bit indicates that the endpoint is disabled per the application's request.

Bit 0 **XFRC**: Transfer completed interrupt

This field indicates that the programmed transfer is complete on the AHB as well as on the USB, for this endpoint.

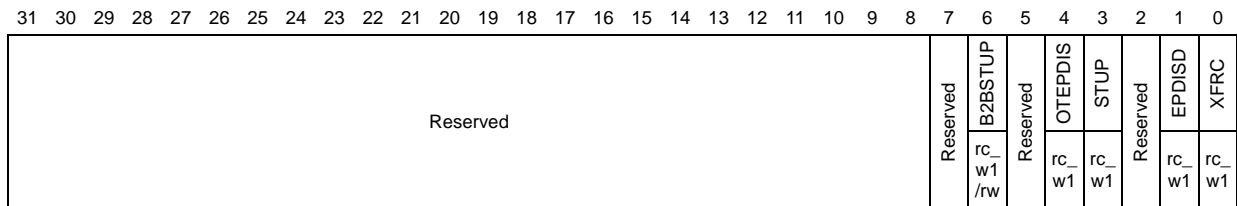


**OTG\_FS device endpoint-x interrupt register (OTG\_FS\_DOEPINTx) (x = 0..3, where x = Endpoint\_number)**

Address offset: 0xB08 + (Endpoint\_number × 0x20)

Reset value: 0x0000 0080

This register indicates the status of an endpoint with respect to USB- and AHB-related events. It is shown in *Figure 250*. The application must read this register when the OUT Endpoints Interrupt bit of the OTG\_FS\_GINTSTS register (OEPINT bit in OTG\_FS\_GINTSTS) is set. Before the application can read this register, it must first read the OTG\_FS\_DAINR register to get the exact endpoint number for the OTG\_FS\_DOEPINTx register. The application must clear the appropriate bit in this register to clear the corresponding bits in the OTG\_FS\_DAINR and OTG\_FS\_GINTSTS registers.



Bits 31:7 Reserved, must be kept at reset value.

- Bit 6 **B2BSTUP**: Back-to-back SETUP packets received  
 Applies to control OUT endpoint only.  
 This bit indicates that the core has received more than three back-to-back SETUP packets for this particular endpoint.
- Bit 5 Reserved, must be kept at reset value.
- Bit 4 **OTEPDIS**: OUT token received when endpoint disabled  
 Applies only to control OUT endpoints.  
 Indicates that an OUT token was received when the endpoint was not yet enabled. This interrupt is asserted on the endpoint for which the OUT token was received.
- Bit 3 **STUP**: SETUP phase done  
 Applies to control OUT endpoint only.  
 Indicates that the SETUP phase for the control endpoint is complete and no more back-to-back SETUP packets were received for the current control transfer. On this interrupt, the application can decode the received SETUP data packet.
- Bit 2 Reserved, must be kept at reset value.
- Bit 1 **EPDISD**: Endpoint disabled interrupt  
 This bit indicates that the endpoint is disabled per the application's request.
- Bit 0 **XFRC**: Transfer completed interrupt  
 This field indicates that the programmed transfer is complete on the AHB as well as on the USB, for this endpoint.

**OTG\_FS device IN endpoint 0 transfer size register (OTG\_FS\_DIEPTSIZ0)**

Address offset: 0x910

Reset value: 0x0000 0000

The application must modify this register before enabling endpoint 0. Once endpoint 0 is enabled using the endpoint enable bit in the device control endpoint 0 control registers (EPENA in OTG\_FS\_DIEPCTL0), the core modifies this register. The application can only read this register once the core has cleared the Endpoint enable bit.

Nonzero endpoints use the registers for endpoints 1–3.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved											PKTCNT		Reserved											XFRSIZ							
											rw	rw												rw	rw	rw	rw	rw	rw	rw	

Bits 31:21 Reserved, must be kept at reset value.

Bits 20:19 **PKTCNT**: Packet count

Indicates the total number of USB packets that constitute the Transfer Size amount of data for endpoint 0.

This field is decremented every time a packet (maximum size or short packet) is read from the TxFIFO.

Bits 18:7 Reserved, must be kept at reset value.

Bits 6:0 **XFRSIZ**: Transfer size

Indicates the transfer size in bytes for endpoint 0. The core interrupts the application only after it has exhausted the transfer size amount of data. The transfer size can be set to the maximum packet size of the endpoint, to be interrupted at the end of each packet.

The core decrements this field every time a packet from the external memory is written to the TxFIFO.

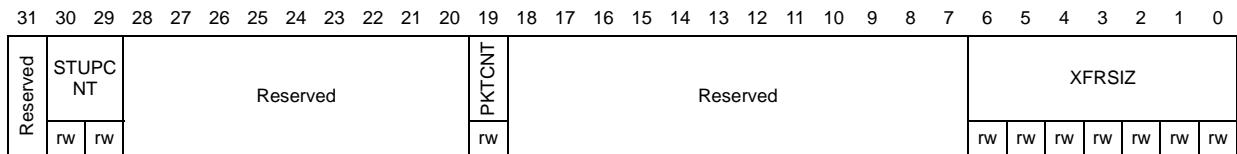
**OTG\_FS device OUT endpoint 0 transfer size register (OTG\_FS\_DOEPTSIZ0)**

Address offset: 0xB10

Reset value: 0x0000 0000

The application must modify this register before enabling endpoint 0. Once endpoint 0 is enabled using the Endpoint enable bit in the OTG\_FS\_DOEPCNTL0 registers (EPENA bit in OTG\_FS\_DOEPCNTL0), the core modifies this register. The application can only read this register once the core has cleared the Endpoint enable bit.

Nonzero endpoints use the registers for endpoints 1–3.



Bit 31 Reserved, must be kept at reset value.

Bits 30:29 **STUPCNT**: SETUP packet count

This field specifies the number of back-to-back SETUP data packets the endpoint can receive.

- 01: 1 packet
- 10: 2 packets
- 11: 3 packets

Bits 28:20 Reserved, must be kept at reset value.

Bit 19 **PKTCNT**: Packet count

This field is decremented to zero after a packet is written into the RxFIFO.

Bits 18:7 Reserved, must be kept at reset value.

Bits 6:0 **XFRSIZ**: Transfer size

Indicates the transfer size in bytes for endpoint 0. The core interrupts the application only after it has exhausted the transfer size amount of data. The transfer size can be set to the maximum packet size of the endpoint, to be interrupted at the end of each packet. The core decrements this field every time a packet is read from the RxFIFO and written to the external memory.

**OTG\_FS device endpoint-x transfer size register (OTG\_FS\_DIEPTSIZx)  
(x = 1..3, where x = Endpoint\_number)**

Address offset: 0x910 + (Endpoint\_number × 0x20)

Reset value: 0x0000 0000

The application must modify this register before enabling the endpoint. Once the endpoint is enabled using the Endpoint enable bit in the OTG\_FS\_DIEPCTLx registers (EPENA bit in OTG\_FS\_DIEPCTLx), the core modifies this register. The application can only read this register once the core has cleared the Endpoint enable bit.

	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved	MCNT		PKTCNT											XFRSIZ																		
	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	r/w	

Bit 31 Reserved, must be kept at reset value.

Bits 30:29 **MCNT**: Multi count

For periodic IN endpoints, this field indicates the number of packets that must be transmitted per frame on the USB. The core uses this field to calculate the data PID for isochronous IN endpoints.

- 01: 1 packet
- 10: 2 packets
- 11: 3 packets

Bit 28:19 **PKTCNT**: Packet count

Indicates the total number of USB packets that constitute the Transfer Size amount of data for this endpoint.

This field is decremented every time a packet (maximum size or short packet) is read from the Tx FIFO.

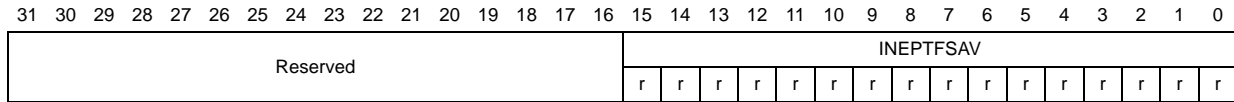
Bits 18:0 **XFRSIZ**: Transfer size

This field contains the transfer size in bytes for the current endpoint. The core only interrupts the application after it has exhausted the transfer size amount of data. The transfer size can be set to the maximum packet size of the endpoint, to be interrupted at the end of each packet.

The core decrements this field every time a packet from the external memory is written to the Tx FIFO.

**OTG\_FS device IN endpoint transmit FIFO status register (OTG\_FS\_DTXFSTSx) (x = 0..3, where x = Endpoint\_number)**

Address offset for IN endpoints: 0x918 + (Endpoint\_number × 0x20) This read-only register contains the free space information for the Device IN endpoint TxFIFO.



31:16 Reserved, must be kept at reset value.

15:0 **INEPTFSAV**: IN endpoint TxFIFO space available

Indicates the amount of free space available in the Endpoint TxFIFO.

Values are in terms of 32-bit words:

0x0: Endpoint TxFIFO is full

0x1: 1 word available

0x2: 2 words available

0xn: n words available

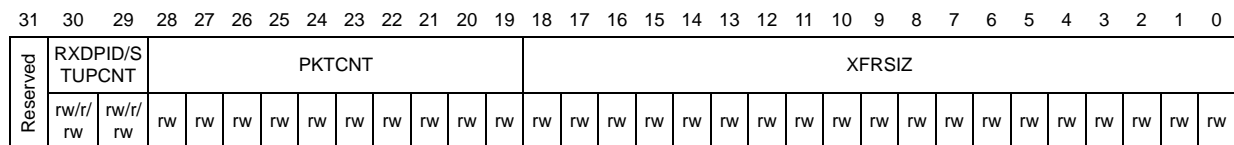
Others: Reserved

**OTG\_FS device OUT endpoint-x transfer size register (OTG\_FS\_DOEPTSIZx) (x = 1..3, where x = Endpoint\_number)**

Address offset: 0xB10 + (Endpoint\_number × 0x20)

Reset value: 0x0000 0000

The application must modify this register before enabling the endpoint. Once the endpoint is enabled using Endpoint Enable bit of the OTG\_FS\_DOEPCCTLx registers (EPENA bit in OTG\_FS\_DOEPCCTLx), the core modifies this register. The application can only read this register once the core has cleared the Endpoint enable bit.



Bit 31 Reserved, must be kept at reset value.

Bits 30:29 **RXDPID**: Received data PID

Applies to isochronous OUT endpoints only.

This is the data PID received in the last packet for this endpoint.

00: DATA0

01: DATA2

10: DATA1

11: MDATA

**STUPCNT:** SETUP packet count

Applies to control OUT Endpoints only.

This field specifies the number of back-to-back SETUP data packets the endpoint can receive.

- 01: 1 packet
- 10: 2 packets
- 11: 3 packets

Bit 28:19 **PKTCNT:** Packet count

Indicates the total number of USB packets that constitute the Transfer Size amount of data for this endpoint.

This field is decremented every time a packet (maximum size or short packet) is written to the RxFIFO.

Bits 18:0 **XFRSIZ:** Transfer size

This field contains the transfer size in bytes for the current endpoint. The core only interrupts the application after it has exhausted the transfer size amount of data. The transfer size can be set to the maximum packet size of the endpoint, to be interrupted at the end of each packet.

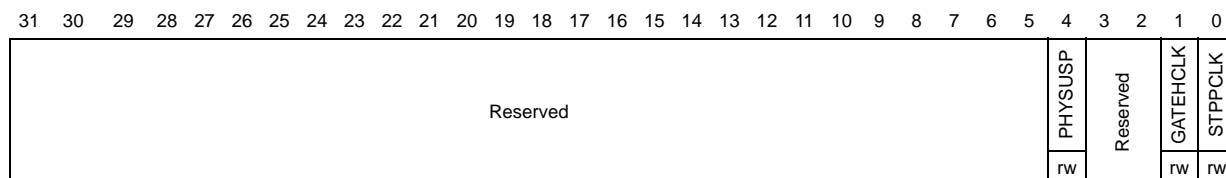
The core decrements this field every time a packet is read from the RxFIFO and written to the external memory.

### 22.16.5 OTG\_FS power and clock gating control register (OTG\_FS\_PCGCCTL)

Address offset: 0xE00

Reset value: 0x0000 0000

This register is available in host and device modes.



Bit 31:5 Reserved, must be kept at reset value.

Bit 4 **PHYSUSP:** PHY Suspended

Indicates that the PHY has been suspended. This bit is updated once the PHY is suspended after the application has set the STPPCLK bit (bit 0).

Bits 3:2 Reserved, must be kept at reset value.

Bit 1 **GATEHCLK:** Gate HCLK

The application sets this bit to gate HCLK to modules other than the AHB Slave and Master and wakeup logic when the USB is suspended or the session is not valid. The application clears this bit when the USB is resumed or a new session starts.

Bit 0 **STPPCLK:** Stop PHY clock

The application sets this bit to stop the PHY clock when the USB is suspended, the session is not valid, or the device is disconnected. The application clears this bit when the USB is resumed or a new session starts.



### 22.16.6 OTG\_FS register map

The table below gives the USB OTG register map and reset values.

**Table 133. OTG\_FS register map and reset values**

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0											
0x000	OTG_FS_GOT_GCTL	Reserved													BSVLD	Reserved						Reserved						SRQ	SRQSCS															
	Reset value														0	0	0	1							0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0				
0x004	OTG_FS_GOT_GINT	Reserved													DBCNE	ADTOCHG	HNGDET	Reserved						HNSSCHG		SRSSCHG	Reserved						SEDET	Res.										
	Reset value														0	0	0							0	0	0							0											
0x008	OTG_FS_GAH_BCFG	Reserved																										PTXFELVL	TXFELVL	Reserved		GINTMSK												
	Reset value																											0	0			0												
0x00C	OTG_FS_GUS_BCFG	CTXPKT	FDMOD	FHMOD	Reserved													TRDT			HNPCAP	SRPCAP	Reserved	PHYSEL	Reserved	TOTAL																		
	Reset value																	0	1	0	1	0	0	Reserved	1	0			0	0	0													
0x010	OTG_FS_GRS_TCTL	AHBIDL	Reserved													TXFNUM			RXFFLSH	Reserved	FCRST	HSRST	CSRST																					
	Reset value	1														0	0	0	0	0	0	0	0	0																				
0x014	OTG_FS_GIN_TSTS	WKUINT	SRQINT	DISCINT	CIDSCHG	Reserved	PTXFE	HCINT	HPRTINT	Reserved			IPXFR/ISOXFR	ISOXFR	OEPIINT	IEPIINT	Reserved			EOPF	ISODRPM	ENUNDMEM	USBRST	USBSUSP	ESUSP	Reserved			GOUTNAKEFF	GINAKEFF	NPTXFE	RXFLVL	SOF	OTGINT	MMIS	CMOD								
	Reset value	0	0	0	0		1	0	0				0	0	0	0				0	0	0	0	0	0				0	0	1	0	0	0	0	0	0							
0x018	OTG_FS_GIN_TMSK	WUIM	SRQIM	DISCINT	CIDSCGM	Reserved	PTXFEM	HCIM	PRTIM	Reserved			IPXFRM/ISOXFRM	ISOXFRM	OEPIINT	IEPIINT	EPMISM	Reserved			EOPFM	ISODRPM	ENUNDMEM	USBRST	USBSUSPM	ESUSPM	Reserved			GONAKEFFM	GINAKEFFM	NPTXFEM	RXFLVLM	SOFM	OTGINT	MMISM	Reserved							
	Reset value	0	0	0	0		0	0	0				0	0	0	0					0	0	0	0	0	0				0	0	0	0	0	0	0	0	0	0					
0x01C	OTG_FS_GRX_STSR (host mode)	Reserved													PKTSTS			DPID	BCNT						CHNUM																			
	Reset value														0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	OTG_FS_GRX_STSR (Device mode)	Reserved									FRMNUM			PKTSTS			DPID	BCNT						EPNUM																				
	Reset value										0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0				



Table 133. OTG\_FS register map and reset values (continued)

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0														
0x020	OTG_FS_GRX STSR (host mode)	Reserved											PKTSTS		DPID	BCNT								CHNUM																							
	Reset value												0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0					
0x020	OTG_FS_GRX STSPR (Device mode)	Reserved								FRMNUM			PKTSTS		DPID	BCNT								EPNUM																							
	Reset value									0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0								
0x024	OTG_FS_GRX FSIZ	Reserved														RXFD																															
	Reset value															0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x028	OTG_FS_HNP TXFSIZ/ OTG_FS_DIE PTXF0	NPTXFD/TX0FD														NPTXFSA/TX0FSA																															
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0											
0x02C	OTG_FS_HNP TXSTS	Res.	NPTXQTOP						NPTQXSAV						NPTXFSAV																																
	Reset value		0	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0											
0x038	OTG_FS_GCCFG	Reserved										NOVBUSSENS	SOFOUTEN	VBUSSEN	VBUSASEN	Reserved	PWRDWN	Reserved																													
	Reset value											0	0	0	0		0																														
0x03C	OTG_FS_CID	PRODUCT_ID																																													
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	1	0	0	0	0	0	0	0	0	0	0												
0x100	OTG_FS_HPT XFSIZ	PTXFSIZ														PTXSA																															
	Reset value	0	0	0	0	0	1	1	1	0	1	1	0	1	0	0	0	0	0	0	1	0	0	0	0	0	0	1	0	0	1	0	0	0	0												
0x104	OTG_FS_DIE PTXF1	INEPTXFD														INEPTXSA																															
	Reset value	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0												
0x108	OTG_FS_DIE PTXF2	INEPTXFD														INEPTXSA																															
	Reset value	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0												
0x10C	OTG_FS_DIE PTXF3	INEPTXFD														INEPTXSA																															
	Reset value	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0												
0x400	OTG_FS_HCFG	Reserved																										FSLSS	FSLSPCS																		
	Reset value																											0	0	0																	
0x404	OTG_FS_HFIR	Reserved														FRIVL																															
	Reset value															1	1	1	0	1	0	1	0	0	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	
0x408	OTG_FS_HFN UM	FTREM														FRNUM																															
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1												
0x410	OTG_FS_HPT XSTS	PTXQTOP						PTXQSAV						PTXFSAVL																																	
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0												
0x414	OTG_FS_HAINT	Reserved														HAINT																															
	Reset value															0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0





Table 133. OTG\_FS register map and reset values (continued)

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0															
0x418	OTG_FS_HAI NTMSK	Reserved																HAINTM																														
	Reset value																	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x440	OTG_FS_HPR T	Reserved													PSP D	PTCTL			PPWR	PLSTS	Reserved	PRST	PSUSP	PRES	POCCHNG	POCA	PENCHNG	PENA	PCDET	PCSTS																		
	Reset value														0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0		
0x500	OTG_FS_HCC HAR0	CHENA	CHDIS	ODDFRM	DAD						MCN T	EPTYP	LSDEV	Reserved	EPDIR	EPNUM	MPSIZ																															
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0												
0x520	OTG_FS_HCC HAR1	CHENA	CHDIS	ODDFRM	DAD						MCN T	EPTYP	LSDEV	Reserved	EPDIR	EPNUM	MPSIZ																															
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0												
0x540	OTG_FS_HCC HAR2	CHENA	CHDIS	ODDFRM	DAD						MCN T	EPTYP	LSDEV	Reserved	EPDIR	EPNUM	MPSIZ																															
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0												
0x560	OTG_FS_HCC HAR3	CHENA	CHDIS	ODDFRM	DAD						MCN T	EPTYP	LSDEV	Reserved	EPDIR	EPNUM	MPSIZ																															
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0												
0x580	OTG_FS_HCC HAR4	CHENA	CHDIS	ODDFRM	DAD						MCN T	EPTYP	LSDEV	Reserved	EPDIR	EPNUM	MPSIZ																															
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0												
0x5A0	OTG_FS_HCC HAR5	CHENA	CHDIS	ODDFRM	DAD						MCN T	EPTYP	LSDEV	Reserved	EPDIR	EPNUM	MPSIZ																															
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0												
0x5C0	OTG_FS_HCC HAR6	CHENA	CHDIS	ODDFRM	DAD						MCN T	EPTYP	LSDEV	Reserved	EPDIR	EPNUM	MPSIZ																															
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0												
0x5E0	OTG_FS_HCC HAR7	CHENA	CHDIS	ODDFRM	DAD						MCN T	EPTYP	LSDEV	Reserved	EPDIR	EPNUM	MPSIZ																															
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0												
0x508	OTG_FS_HCI NT0	Reserved																				DTERR	FRMOR	BBERR	TXERR	Reserved	ACK	NAK	STALL	Reserved	CHH	XFRC																
	Reset value																					0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0								
0x528	OTG_FS_HCI NT1	Reserved																				DTERR	FRMOR	BBERR	TXERR	Reserved	ACK	NAK	STALL	Reserved	CHH	XFRC																
	Reset value																					0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0								



Table 133. OTG\_FS register map and reset values (continued)

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0						
0x548	OTG_FS_HCI NT2	Reserved																					DTERR	FRMOR	BBERR	TXERR	Reserved	ACK	NAK	STALL	Reserved	CHH	XFRC						
	Reset value																						0	0	0	0	0	0	0	0	0	0	0						
0x568	OTG_FS_HCI NT3	Reserved																					DTERR	FRMOR	BBERR	TXERR	Reserved	ACK	NAK	STALL	Reserved	CHH	XFRC						
	Reset value																						0	0	0	0	0	0	0	0	0	0	0						
0x588	OTG_FS_HCI NT4	Reserved																					DTERR	FRMOR	BBERR	TXERR	Reserved	ACK	NAK	STALL	Reserved	CHH	XFRC						
	Reset value																						0	0	0	0	0	0	0	0	0	0	0						
0x5A8	OTG_FS_HCI NT5	Reserved																					DTERR	FRMOR	BBERR	TXERR	Reserved	ACK	NAK	STALL	Reserved	CHH	XFRC						
	Reset value																						0	0	0	0	0	0	0	0	0	0	0						
0x5C8	OTG_FS_HCI NT6	Reserved																					DTERR	FRMOR	BBERR	TXERR	Reserved	ACK	NAK	STALL	Reserved	CHH	XFRC						
	Reset value																						0	0	0	0	0	0	0	0	0	0	0						
0x5E8	OTG_FS_HCI NT7	Reserved																					DTERR	FRMOR	BBERR	TXERR	Reserved	ACK	NAK	STALL	Reserved	CHH	XFRC						
	Reset value																						0	0	0	0	0	0	0	0	0	0	0						
0x50C	OTG_FS_HCI NTMSK0	Reserved																					DTERRM	FRMORM	BBERRM	TXERRM	NYET	ACKM	NAKM	STALLM	Reserved	CHHM	XFRCM						
	Reset value																						0	0	0	0	0	0	0	0	0	0	0						
0x52C	OTG_FS_HCI NTMSK1	Reserved																					DTERRM	FRMORM	BBERRM	TXERRM	NYET	ACKM	NAKM	STALLM	Reserved	CHHM	XFRCM						
	Reset value																						0	0	0	0	0	0	0	0	0	0	0						
0x54C	OTG_FS_HCI NTMSK2	Reserved																					DTERRM	FRMORM	BBERRM	TXERRM	NYET	ACKM	NAKM	STALLM	Reserved	CHHM	XFRCM						
	Reset value																						0	0	0	0	0	0	0	0	0	0	0						
0x56C	OTG_FS_HCI NTMSK3	Reserved																					DTERRM	FRMORM	BBERRM	TXERRM	NYET	ACKM	NAKM	STALLM	Reserved	CHHM	XFRCM						
	Reset value																						0	0	0	0	0	0	0	0	0	0	0						
0x58C	OTG_FS_HCI NTMSK4	Reserved																					DTERRM	FRMORM	BBERRM	TXERRM	NYET	ACKM	NAKM	STALLM	Reserved	CHHM	XFRCM						
	Reset value																						0	0	0	0	0	0	0	0	0	0	0						
0x5AC	OTG_FS_HCI NTMSK5	Reserved																					DTERRM	FRMORM	BBERRM	TXERRM	NYET	ACKM	NAKM	STALLM	Reserved	CHHM	XFRCM						
	Reset value																						0	0	0	0	0	0	0	0	0	0	0						

Table 133. OTG\_FS register map and reset values (continued)

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0																
0x5CC	OTG_FS_HCI NTMSK6	Reserved																				DTERRM	FRMORM	BBERRM	TXERRM	NYET	ACKM	NAKM	STALLM	Reserved	CHHM	XFRM																	
	Reset value	0																				0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x5EC	OTG_FS_HCI NTMSK7	Reserved																				DTERRM	FRMORM	BBERRM	TXERRM	NYET	ACKM	NAKM	STALLM	Reserved	CHHM	XFRM																	
	Reset value	0																				0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x510	OTG_FS_HCT SIZ0	Reserved	DPID	PKTCNT										XFRSIZ																																			
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0															
0x530	OTG_FS_HCT SIZ1	Reserved	DPID	PKTCNT										XFRSIZ																																			
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0															
0x550	OTG_FS_HCT SIZ2	Reserved	DPID	PKTCNT										XFRSIZ																																			
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0															
0x570	OTG_FS_HCT SIZ3	Reserved	DPID	PKTCNT										XFRSIZ																																			
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0															
0x590	OTG_FS_HCT SIZ4	Reserved	DPID	PKTCNT										XFRSIZ																																			
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0															
0x5B0	OTG_FS_HCT SIZ5	Reserved	DPID	PKTCNT										XFRSIZ																																			
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0															
0x5D0	OTG_FS_HCT SIZ6	Reserved	DPID	PKTCNT										XFRSIZ																																			
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0															
0x5F0	OTG_FS_HCT SIZ7	Reserved	DPID	PKTCNT										XFRSIZ																																			
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0															
0x800	OTG_FS_DCF G	Reserved																				PFIVL		DAD				Reserved	NZLSOHSK		DSPD																		
	Reset value	0																				0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x804	OTG_FS_DCT L	Reserved																				POPRGDNE	CGONAK	SGONAK	CGINAK	SGINAK	TCTL		GONSTS	GINSTS	SDIS	RWUSIG																	
	Reset value	0																				0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x808	OTG_FS_DST S	Reserved										FNSOF										Reserved				EERR	ENUMSPD	SUSPSTS																					
	Reset value	0										0										0				0	0	0																					



Table 133. OTG\_FS register map and reset values (continued)

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0						
0x810	OTG_FS_DIE_PMSK	Reserved																								INEPNEM	INEPNMM	ITTXFEMSK	TOM	Reserved	EPDM	XFCRM							
	Reset value																									0	0	0	0	0	0								
0x814	OTG_FS_DOE_PMSK	Reserved																								OTEPDM	STUPM	Reserved	EPDM	XFCRM									
	Reset value																									0	0	0	0										
0x818	OTG_FS_DAI_NT	OEPINT												IEPINT																									
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0							
0x81C	OTG_FS_DAI_NTMSK	OEPM												IEPM																									
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0							
0x828	OTG_FS_DVB_USDIS	Reserved												VBUSDT																									
	Reset value													0	0	0	1	0	1	1	1	1	1	1	0	1	0	1	1	1	1								
0x82C	OTG_FS_DVB_USPULSE	Reserved												DVBUSP																									
	Reset value													0	1	0	1	1	0	1	1	1	1	0	0	0													
0x834	OTG_FS_DIE_PEMPMSK	Reserved												INEPTXFEM																									
	Reset value													0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0								
0x900	OTG_FS_DIE_PCTL0	EPENA	EPDIS	Reserved	SNAK	CNAK	TXFNUM	Stall	Reserved	EPTYP	NAKSTS	Reserved	USBAEP	Reserved												MPSIZ													
	Reset value	0	0		0	0	0	0	0	0	0	0	0	1													0	0											
0x918	TG_FS_DTXF_STS0	Reserved												INEPTFSAV																									
	Reset value													0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0								
0x920	OTG_FS_DIE_PCTL1	EPENA	EPDIS	SODDFRM/SD1PID	SD0PID/SEVNFRM	SNAK	CNAK	TXFNUM	Stall	Reserved	EPTYP	NAKSTS	EONUM/DPID	USBAEP	Reserved												MPSIZ												
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0													0	0	0	0	0	0	0	0	0	0	0	0	0
0x938	TG_FS_DTXF_STS1	Reserved												INEPTFSAV																									
	Reset value													0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0								
0x940	OTG_FS_DIE_PCTL2	EPENA	EPDIS	SODDFRM	SD0PID/SEVNFRM	SNAK	CNAK	TXFNUM	Stall	Reserved	EPTYP	NAKSTS	EONUM/DPID	USBAEP	Reserved												MPSIZ												
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0													0	0	0	0	0	0	0	0	0	0	0	0	0
0x958	TG_FS_DTXF_STS2	Reserved												INEPTFSAV																									
	Reset value													0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0								



Table 133. OTG\_FS register map and reset values (continued)

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0			
0x960	OTG_FS_DIE_PCTL3	EPENA	EPDIS	SODDFRM	SD0PID/SEVNFIRM	SNAK	CNAK	TXFNUM				Stall	Reserved	EPTYP		NAKSTS		EONUM/DPID	USBAEP	Reserved				MPSIZ												
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0			
0x978	TG_FS_DTXF_STS3	Reserved																	INEPTFSAV																	
	Reset value	0																	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0xB00	OTG_FS_DOE_PCTL0	EPENA	EPDIS	Reserved		SNAK	CNAK	Reserved				Stall	SNPM	EPTYP		NAKSTS		Reserved	USBAEP	Reserved								MPSIZ								
	Reset value	0	0	0		0	0	0				0	0	0		0		0	1	0								0								
0xB20	OTG_FS_DOE_PCTL1	EPENA	EPDIS	SODDFRM	SD0PID/SEVNFIRM	SNAK	CNAK	Reserved				Stall	SNPM	EPTYP		NAKSTS		EONUM/DPID	USBAEP	Reserved				MPSIZ												
	Reset value	0	0	0	0	0	0	0				0	0	0		0		0	0	0				0												
0xB40	OTG_FS_DOE_PCTL2	EPENA	EPDIS	SODDFRM	SD0PID/SEVNFIRM	SNAK	CNAK	Reserved				Stall	SNPM	EPTYP		NAKSTS		EONUM/DPID	USBAEP	Reserved				MPSIZ												
	Reset value	0	0	0	0	0	0	0				0	0	0		0		0	0	0				0												
0xB60	OTG_FS_DOE_PCTL3	EPENA	EPDIS	SODDFRM	SD0PID/SEVNFIRM	SNAK	CNAK	Reserved				Stall	SNPM	EPTYP		NAKSTS		EONUM/DPID	USBAEP	Reserved				MPSIZ												
	Reset value	0	0	0	0	0	0	0				0	0	0		0		0	0	0				0												
0x908	OTG_FS_DIE_PINT0	Reserved																								TXFE	INEPNE	Reserved	ITTXFE	TOC	Reserved	EPDIS	XFRC			
	Reset value	0																								1	0	0	0	0	0	0	0			
0x928	OTG_FS_DIE_PINT1	Reserved																								TXFE	INEPNE	Reserved	ITTXFE	TOC	Reserved	EPDIS	XFRC			
	Reset value	0																								1	0	0	0	0	0	0	0			
0x948	OTG_FS_DIE_PINT2	Reserved																								TXFE	INEPNE	Reserved	ITTXFE	TOC	Reserved	EPDIS	XFRC			
	Reset value	0																								1	0	0	0	0	0	0	0			
0x968	OTG_FS_DIE_PINT3	Reserved																								TXFE	INEPNE	Reserved	ITTXFE	TOC	Reserved	EPDIS	XFRC			
	Reset value	0																								1	0	0	0	0	0	0	0			



Table 133. OTG\_FS register map and reset values (continued)

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0																							
0xB08	OTG_FS_DOE_PINT0	Reserved																								Reserved	B2BSTUP	Reserved	OTEPDIS	STUP	Reserved	EPDISD	XFRC																							
	Reset value																									0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0xB28	OTG_FS_DOE_PINT1	Reserved																								Reserved	B2BSTUP	Reserved	OTEPDIS	STUP	Reserved	EPDISD	XFRC																							
	Reset value																									0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0xB48	OTG_FS_DOE_PINT2	Reserved																								Reserved	B2BSTUP	Reserved	OTEPDIS	STUP	Reserved	EPDISD	XFRC																							
	Reset value																									0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0xB68	OTG_FS_DOE_PINT3	Reserved																								Reserved	B2BSTUP	Reserved	OTEPDIS	STUP	Reserved	EPDISD	XFRC																							
	Reset value																									0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0x910	OTG_FS_DIE_PTSIZ0	Reserved											PKT CNT		Reserved											XFRSIZ																														
	Reset value												0	0												0	0	0	0	0	0	0	0																							
0x930	OTG_FS_DIE_PTSIZ1	Reserved	MCN T	PKTCNT											XFRSIZ																																									
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0																					
0x950	OTG_FS_DIE_PTSIZ2	Reserved	MCN T	PKTCNT											XFRSIZ																																									
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0																				
0x970	OTG_FS_DIE_PTSIZ3	Reserved	MCN T	PKTCNT											XFRSIZ																																									
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0																				
0xB10	OTG_FS_DOE_PTSIZ0	Reserved	STUPCN T	Reserved											PKTCNT	Reserved											XFRSIZ																													
	Reset value	0	0												0												0	0	0	0	0	0	0	0																						
0xB30	OTG_FS_DOE_PTSIZ1	Reserved	RXDPID/ STUPCNT	PKTCNT											XFRSIZ																																									
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0																				
0xB50	OTG_FS_DOE_PTSIZ2	Reserved	RXDPID/ STUPCNT	PKTCNT											XFRSIZ																																									
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0																			
0xB70	OTG_FS_DOE_PTSIZ3	Reserved	RXDPID/ STUPCNT	PKTCNT											XFRSIZ																																									
	Reset value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0																			

Table 133. OTG\_FS register map and reset values (continued)

Offset	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0xE00	OTG_FS_PCG CCTL	Reserved																								PHYSUSP	Reserved	GATEHCLK	STPCLK				
	Reset value																																

Refer to [Table 1 on page 38](#) for the register boundary addresses.

## 22.17 OTG\_FS programming model

### 22.17.1 Core initialization

The application must perform the core initialization sequence. If the cable is connected during power-up, the current mode of operation bit in the OTG\_FS\_GINTSTS (CMOD bit in OTG\_FS\_GINTSTS) reflects the mode. The OTG\_FS controller enters host mode when an "A" plug is connected or device mode when a "B" plug is connected.

This section explains the initialization of the OTG\_FS controller after power-on. The application must follow the initialization sequence irrespective of host or device mode operation. All core global registers are initialized according to the core's configuration:

1. Program the following fields in the OTG\_FS\_GAHBCFG register:
  - Global interrupt mask bit GINTMSK = 1
  - RxFIFO non-empty (RXFLVL bit in OTG\_FS\_GINTSTS)
  - Periodic TxFIFO empty level
2. Program the following fields in the OTG\_FS\_GUSBCFG register:
  - HNP capable bit
  - SRP capable bit
  - FS timeout calibration field
  - USB turnaround time field
3. The software must unmask the following bits in the OTG\_FS\_GINTMSK register:
  - OTG interrupt mask
  - Mode mismatch interrupt mask
4. The software can read the CMOD bit in OTG\_FS\_GINTSTS to determine whether the OTG\_FS controller is operating in host or device mode.



### 22.17.2 Host initialization

To initialize the core as host, the application must perform the following steps:

1. Program the HPRTINT in the OTG\_FS\_GINTMSK register to unmask
2. Program the OTG\_FS\_HCFG register to select full-speed host
3. Program the PPWR bit in OTG\_FS\_HPRT to 1. This drives  $V_{BUS}$  on the USB.
4. Wait for the PCDET interrupt in OTG\_FS\_HPRT0. This indicates that a device is connecting to the port.
5. Program the PRST bit in OTG\_FS\_HPRT to 1. This starts the reset process.
6. Wait at least 10 ms for the reset process to complete.
7. Program the PRST bit in OTG\_FS\_HPRT to 0.
8. Wait for the PENCHNG interrupt in OTG\_FS\_HPRT.
9. Read the PSPD bit in OTG\_FS\_HPRT to get the enumerated speed.
10. Program the HFIR register with a value corresponding to the selected PHY clock 1
11. Program the FSLSPCS field in the OTG\_FS\_HCFG register following the speed of the device detected in step 9. If FSLSPCS has been changed a port reset must be performed.
12. Program the OTG\_FS\_GRXFSIZ register to select the size of the receive FIFO.
13. Program the OTG\_FS\_HNPTXFSIZ register to select the size and the start address of the Non-periodic transmit FIFO for non-periodic transactions.
14. Program the OTG\_FS\_HPTXFSIZ register to select the size and start address of the periodic transmit FIFO for periodic transactions.

To communicate with devices, the system software must initialize and enable at least one channel.

### 22.17.3 Device initialization

The application must perform the following steps to initialize the core as a device on power-up or after a mode change from host to device.

1. Program the following fields in the OTG\_FS\_DCFG register:
  - Device speed
  - Non-zero-length status OUT handshake
2. Program the OTG\_FS\_GINTMSK register to unmask the following interrupts:
  - USB reset
  - Enumeration done
  - Early suspend
  - USB suspend
  - SOF
3. Program the VBUSSEN bit in the OTG\_FS\_GCCFG register to enable  $V_{BUS}$  sensing in “B” device mode and supply the 5 volts across the pull-up resistor on the DP line.
4. Wait for the USBRST interrupt in OTG\_FS\_GINTSTS. It indicates that a reset has been detected on the USB that lasts for about 10 ms on receiving this interrupt.

Wait for the ENUMDNE interrupt in OTG\_FS\_GINTSTS. This interrupt indicates the end of reset on the USB. On receiving this interrupt, the application must read the OTG\_FS\_DSTS register to determine the enumeration speed and perform the steps listed in [Endpoint](#)

*initialization on enumeration completion on page 773.*

At this point, the device is ready to accept SOF packets and perform control transfers on control endpoint 0.

## 22.17.4 Host programming model

### Channel initialization

The application must initialize one or more channels before it can communicate with connected devices. To initialize and enable a channel, the application must perform the following steps:

1. Program the OTG\_FS\_GINTMSK register to unmask the following:
2. Channel interrupt
  - Non-periodic transmit FIFO empty for OUT transactions (applicable when operating in pipelined transaction-level with the packet count field programmed with more than one).
  - Non-periodic transmit FIFO half-empty for OUT transactions (applicable when operating in pipelined transaction-level with the packet count field programmed with more than one).
3. Program the OTG\_FS\_HAINTMSK register to unmask the selected channels' interrupts.
4. Program the OTG\_FS\_HCINTMSK register to unmask the transaction-related interrupts of interest given in the host channel interrupt register.
5. Program the selected channel's OTG\_FS\_HCTSIZx register with the total transfer size, in bytes, and the expected number of packets, including short packets. The application must program the PID field with the initial data PID (to be used on the first OUT transaction or to be expected from the first IN transaction).
6. Program the OTG\_FS\_HCCHARx register of the selected channel with the device's endpoint characteristics, such as type, speed, direction, and so forth. (The channel can be enabled by setting the channel enable bit to 1 only when the application is ready to transmit or receive any packet).

### Halting a channel

The application can disable any channel by programming the OTG\_FS\_HCCHARx register with the CHDIS and CHENA bits set to 1. This enables the OTG\_FS host to flush the posted requests (if any) and generates a channel halted interrupt. The application must wait for the CHH interrupt in OTG\_FS\_HCINTx before reallocating the channel for other transactions. The OTG\_FS host does not interrupt the transaction that has already been started on the USB.

Before disabling a channel, the application must ensure that there is at least one free space available in the non-periodic request queue (when disabling a non-periodic channel) or the periodic request queue (when disabling a periodic channel). The application can simply flush the posted requests when the Request queue is full (before disabling the channel), by programming the OTG\_FS\_HCCHARx register with the CHDIS bit set to 1, and the CHENA bit cleared to 0.

The application is expected to disable a channel on any of the following conditions:

1. When an STALL, TXERR, BBERR or DTERR interrupt in OTG\_FS\_HCINTx is received for an IN or OUT channel. The application must be able to receive other interrupts (DTERR, Nak, Data, TXERR) for the same channel before receiving the halt.
2. When a DISCINT (Disconnect Device) interrupt in OTG\_FS\_GINTSTS is received. (The application is expected to disable all enabled channels).
3. When the application aborts a transfer before normal completion.

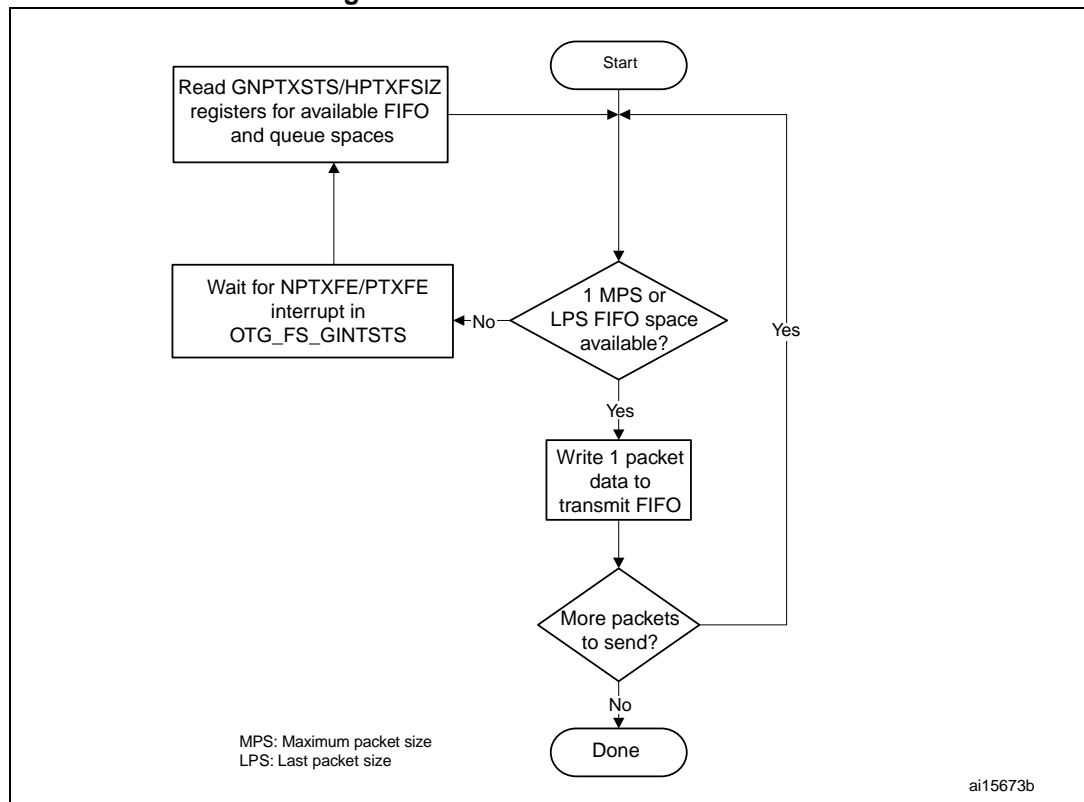
**Operational model**

The application must initialize a channel before communicating to the connected device. This section explains the sequence of operation to be performed for different types of USB transactions.

- **Writing the transmit FIFO**

The OTG\_FS host automatically writes an entry (OUT request) to the periodic/non-periodic request queue, along with the last DWORD write of a packet. The application must ensure that at least one free space is available in the periodic/non-periodic request queue before starting to write to the transmit FIFO. The application must always write to the transmit FIFO in DWORDs. If the packet size is non-DWORD aligned, the application must use padding. The OTG\_FS host determines the actual packet size based on the programmed maximum packet size and transfer size.

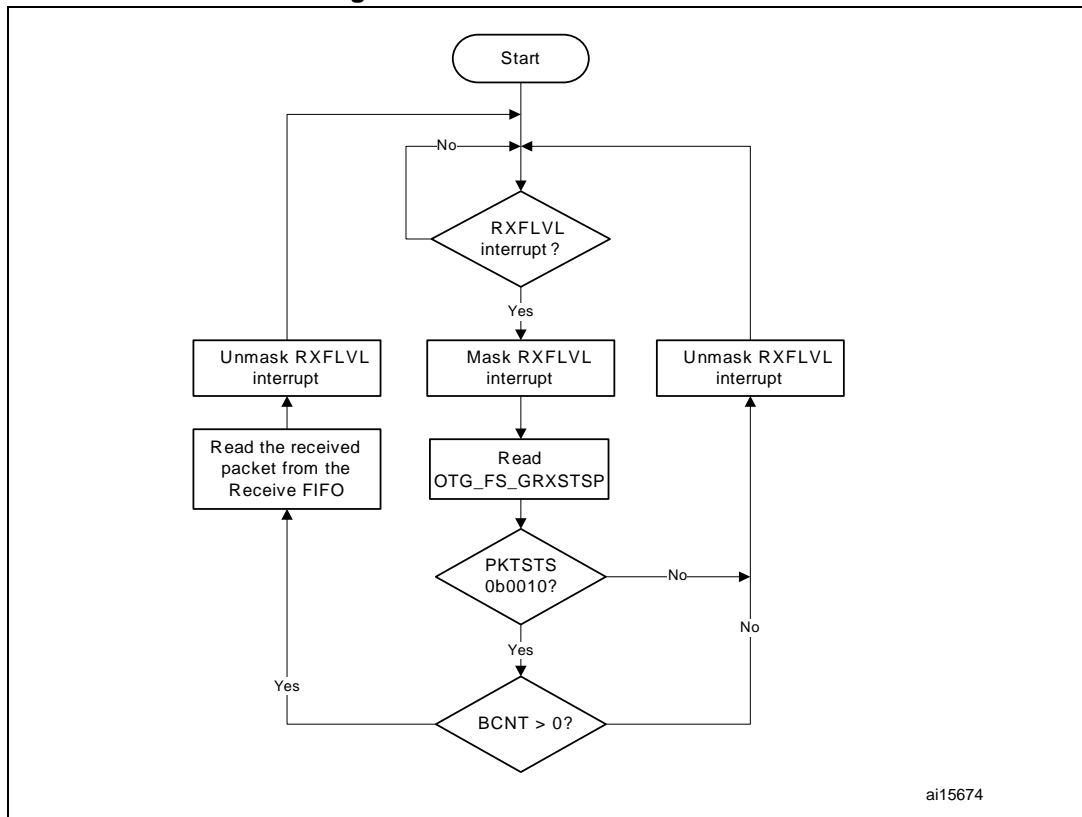
**Figure 252. Transmit FIFO write task**



- **Reading the receive FIFO**

The application must ignore all packet statuses other than IN data packet (bx0010).

**Figure 253. Receive FIFO read task**



- **Bulk and control OUT/SETUP transactions**

A typical bulk or control OUT/SETUP pipelined transaction-level operation is shown in [Figure 254](#). See channel 1 (ch\_1). Two bulk OUT packets are transmitted. A control SETUP transaction operates in the same way but has only one packet. The assumptions are:

- The application is attempting to send two maximum-packet-size packets (transfer size = 1,024 bytes).
- The non-periodic transmit FIFO can hold two packets (128 bytes for FS).
- The non-periodic request queue depth = 4.

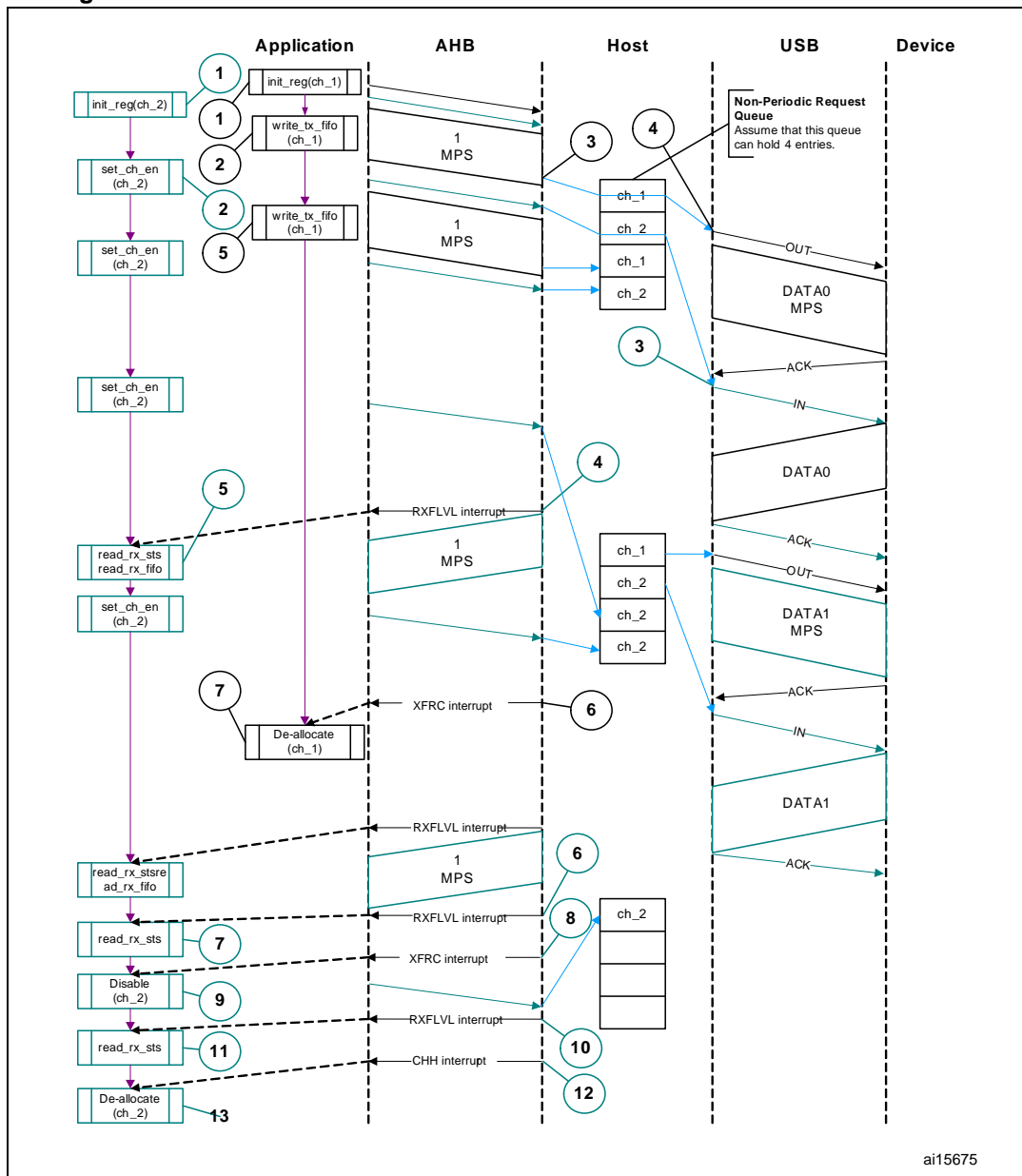
- **Normal bulk and control OUT/SETUP operations**

The sequence of operations in (channel 1) is as follows:

- Initialize channel 1
- Write the first packet for channel 1
- Along with the last Word write, the core writes an entry to the non-periodic request queue
- As soon as the non-periodic queue becomes non-empty, the core attempts to send an OUT token in the current frame
- Write the second (last) packet for channel 1

- f) The core generates the XFRC interrupt as soon as the last transaction is completed successfully
- g) In response to the XFRC interrupt, de-allocate the channel for other transfers
- h) Handling non-ACK responses

**Figure 254. Normal bulk/control OUT/SETUP and bulk/control IN transactions**



The channel-specific interrupt service routine for bulk and control OUT/SETUP transactions is shown in the following code samples.

- **Interrupt service routine for bulk/control OUT/SETUP and bulk/control IN transactions**

- a) Bulk/Control OUT/SETUP

Unmask (NAK/TXERR/STALL/XFRC)

```

if (XFRC)
{
  Reset Error Count
  Mask ACK
  De-allocate Channel
}
else if (STALL)
{
  Transfer Done = 1
  Unmask CHH
  Disable Channel
}
else if (NAK or TXERR )
{
  Rewind Buffer Pointers
  Unmask CHH
  Disable Channel
  if (TXERR)
  {
    Increment Error Count
    Unmask ACK
  }
  else
  {
    Reset Error Count
  }
}
else if (CHH)
{
  Mask CHH
  if (Transfer Done or (Error_count == 3))
  {
    De-allocate Channel
  }
  else
  {
    Re-initialize Channel
  }
}
else if (ACK)
{
  Reset Error Count
  Mask ACK
}

```

The application is expected to write the data packets into the transmit FIFO as and when the space is available in the transmit FIFO and the Request queue. The application can make use of the NPTXFE interrupt in OTG\_FS\_GINTSTS to find the transmit FIFO space.

b) Bulk/Control IN

```

Unmask (TXERR/XFRC/BBERR/STALL/DTERR)
if (XFRC)

```

```

    {
    Reset Error Count
    Unmask CHH
    Disable Channel
    Reset Error Count
    Mask ACK
    }
else if (TXERR or BBERR or STALL)
    {
    Unmask CHH
    Disable Channel
    if (TXERR)
        {
        Increment Error Count
        Unmask ACK
        }
    }
else if (CHH)
    {
    Mask CHH
    if (Transfer Done or (Error_count == 3))
        {
        De-allocate Channel
        }
    else
        {
        Re-initialize Channel
        }
    }
else if (ACK)
    {
    Reset Error Count
    Mask ACK
    }
else if (DTERR)
    {
    Reset Error Count
    }

```

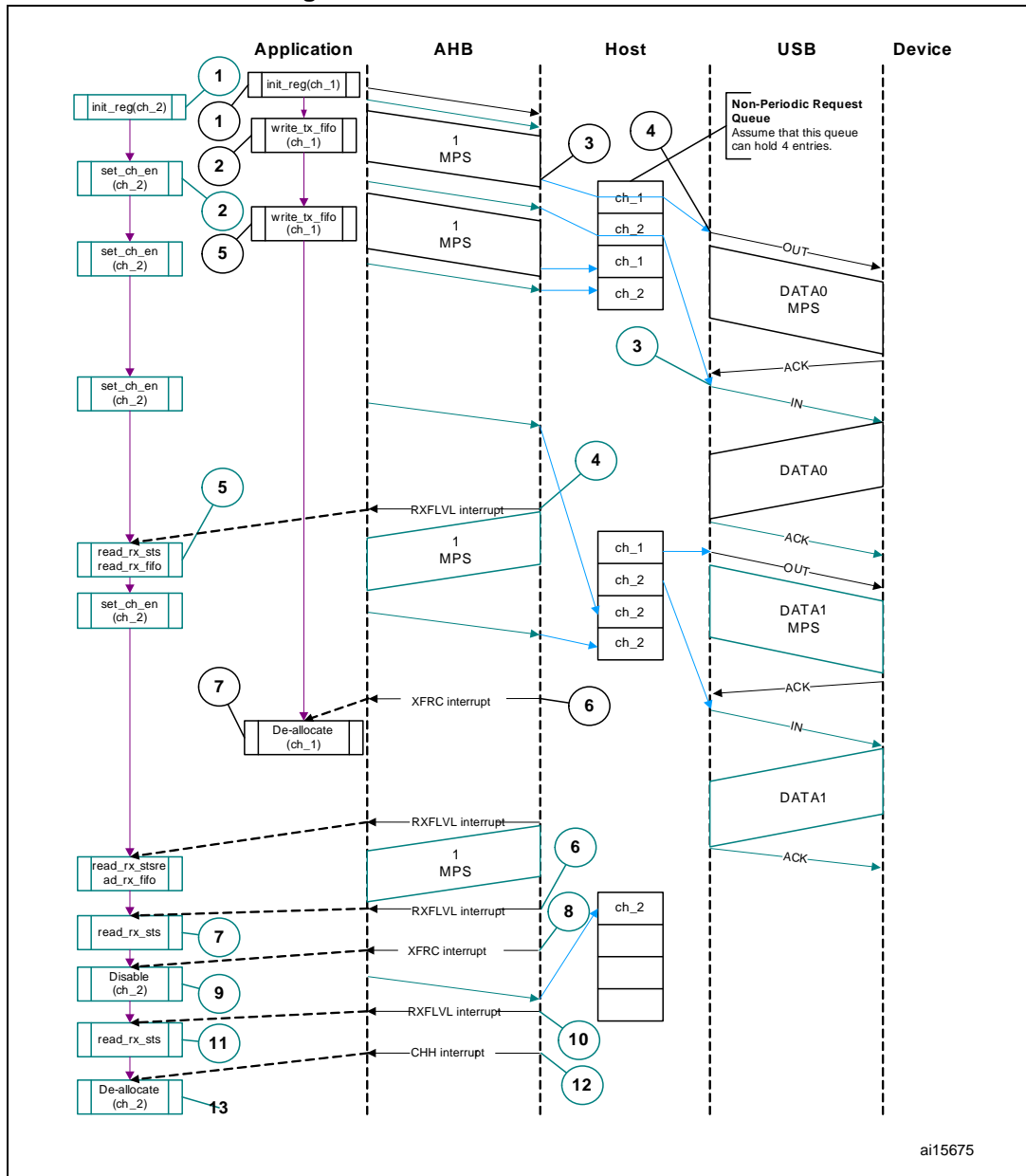
The application is expected to write the requests as and when the Request queue space is available and until the XFRC interrupt is received.

- **Bulk and control IN transactions**

A typical bulk or control IN pipelined transaction-level operation is shown in [Figure 255](#). See channel 2 (ch\_2). The assumptions are:

- The application is attempting to receive two maximum-packet-size packets (transfer size = 1 024 bytes).
- The receive FIFO can contain at least one maximum-packet-size packet and two status Words per packet (72 bytes for FS).
- The non-periodic request queue depth = 4.

Figure 255. Bulk/control IN transactions



The sequence of operations is as follows:

- a) Initialize channel 2.
- b) Set the CHENA bit in HCCHAR2 to write an IN request to the non-periodic request queue.
- c) The core attempts to send an IN token after completing the current OUT transaction.
- d) The core generates an RXFLVL interrupt as soon as the received packet is written to the receive FIFO.
- e) In response to the RXFLVL interrupt, mask the RXFLVL interrupt and read the received packet status to determine the number of bytes received, then read the receive FIFO accordingly. Following this, unmask the RXFLVL interrupt.



- f) The core generates the RXFLVL interrupt for the transfer completion status entry in the receive FIFO.
  - g) The application must read and ignore the receive packet status when the receive packet status is not an IN data packet (PKTSTS in GRXSTSR  $\neq$  0b0010).
  - h) The core generates the XFRC interrupt as soon as the receive packet status is read.
  - i) In response to the XFRC interrupt, disable the channel and stop writing the OTG\_FS\_HCCHAR2 register for further requests. The core writes a channel disable request to the non-periodic request queue as soon as the OTG\_FS\_HCCHAR2 register is written.
  - j) The core generates the RXFLVL interrupt as soon as the halt status is written to the receive FIFO.
  - k) Read and ignore the receive packet status.
  - l) The core generates a CHH interrupt as soon as the halt status is popped from the receive FIFO.
  - m) In response to the CHH interrupt, de-allocate the channel for other transfers.
  - n) Handling non-ACK responses
- **Control transactions**

Setup, Data, and Status stages of a control transfer must be performed as three separate transfers. Setup-, Data- or Status-stage OUT transactions are performed similarly to the bulk OUT transactions explained previously. Data- or Status-stage IN transactions are performed similarly to the bulk IN transactions explained previously. For all three stages, the application is expected to set the EPTYP field in OTG\_FS\_HCCHAR1 to Control. During the Setup stage, the application is expected to set the PID field in OTG\_FS\_HCTSIZ1 to SETUP.
  - **Interrupt OUT transactions**

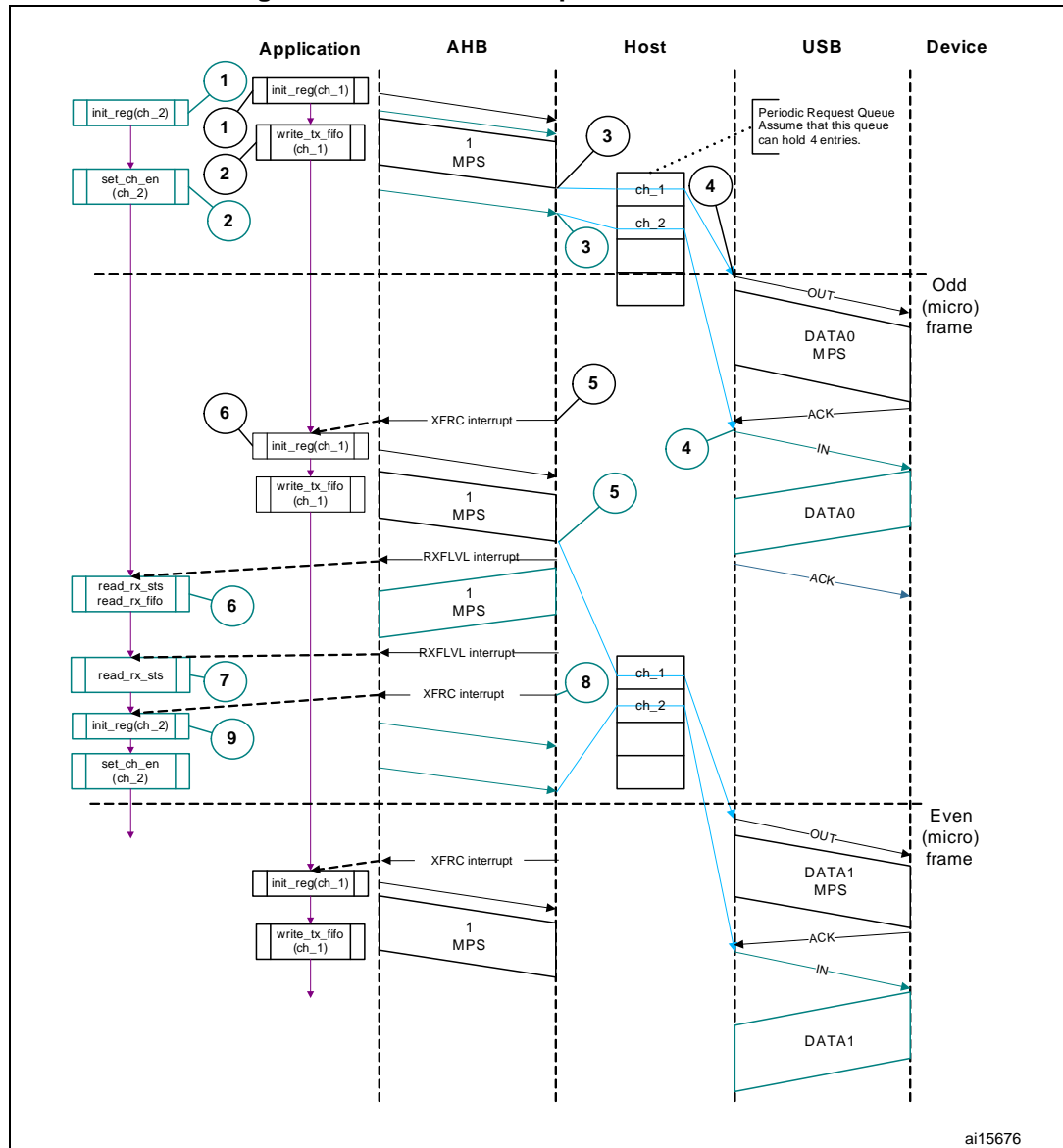
A typical interrupt OUT operation is shown in [Figure 256](#). The assumptions are:

    - The application is attempting to send one packet in every frame (up to 1 maximum packet size), starting with the odd frame (transfer size = 1 024 bytes)
    - The periodic transmit FIFO can hold one packet (1 KB)
    - Periodic request queue depth = 4

The sequence of operations is as follows:

    - a) Initialize and enable channel 1. The application must set the ODDFRM bit in OTG\_FS\_HCCHAR1.
    - b) Write the first packet for channel 1.
    - c) Along with the last Word write of each packet, the OTG\_FS host writes an entry to the periodic request queue.
    - d) The OTG\_FS host attempts to send an OUT token in the next (odd) frame.
    - e) The OTG\_FS host generates an XFRC interrupt as soon as the last packet is transmitted successfully.
    - f) In response to the XFRC interrupt, reinitialize the channel for the next transfer.

Figure 256. Normal interrupt OUT/IN transactions



- Interrupt service routine for interrupt OUT/IN transactions
  - a) Interrupt OUT

```

Unmask (NAK/TXERR/STALL/XFRC/FRMOR)
if (XFRC)
{
    Reset Error Count
    Mask ACK
    De-allocate Channel
}
else
    if (STALL or FRMOR)
    {
        Mask ACK
        Unmask CHH
    }
    
```

```

Disable Channel
if (STALL)
{
Transfer Done = 1
}
}
else
if (NAK or TXERR)
{
Rewind Buffer Pointers
Reset Error Count
Mask ACK
Unmask CHH
Disable Channel
}
else
if (CHH)
{
Mask CHH
if (Transfer Done or (Error_count == 3))
{
De-allocate Channel
}
else
{
Re-initialize Channel (in next b_interval - 1 Frame)
}
}
else
if (ACK)
{
Reset Error Count
Mask ACK
}

```

The application uses the NPTXFE interrupt in OTG\_FS\_GINTSTS to find the transmit FIFO space.

#### b) Interrupt IN

```

Unmask (NAK/TXERR/XFRC/BBERR/STALL/FRMOR/DTERR)
if (XFRC)
{
Reset Error Count
Mask ACK
if (OTG_FS_HCTSIZx.PKTCNT == 0)
{
De-allocate Channel
}
}
else
{
Transfer Done = 1
Unmask CHH
Disable Channel
}

```

```

    }
  }
else
  if (STALL or FRMOR or NAK or DTERR or BBERR)
  {
    Mask ACK
    Unmask CHH
    Disable Channel
    if (STALL or BBERR)
    {
      Reset Error Count
      Transfer Done = 1
    }
    else
      if (!FRMOR)
      {
        Reset Error Count
      }
  }
else
  if (TXERR)
  {
    Increment Error Count
    Unmask ACK
    Unmask CHH
    Disable Channel
  }
else
  if (CHH)
  {
    Mask CHH
    if (Transfer Done or (Error_count == 3))
    {
      De-allocate Channel
    }
    else
      Re-initialize Channel (in next b_interval - 1 /Frame)
  }
}
else
  if (ACK)
  {
    Reset Error Count
    Mask ACK

```

}

- **Interrupt IN transactions**

The assumptions are:

- The application is attempting to receive one packet (up to 1 maximum packet size) in every frame, starting with odd (transfer size = 1 024 bytes).
- The receive FIFO can hold at least one maximum-packet-size packet and two status Words per packet (1 031 bytes).
- Periodic request queue depth = 4.

- **Normal interrupt IN operation**

The sequence of operations is as follows:

- a) Initialize channel 2. The application must set the ODDFRM bit in OTG\_FS\_HCCHAR2.
- b) Set the CHENA bit in OTG\_FS\_HCCHAR2 to write an IN request to the periodic request queue.
- c) The OTG\_FS host writes an IN request to the periodic request queue for each OTG\_FS\_HCCHAR2 register write with the CHENA bit set.
- d) The OTG\_FS host attempts to send an IN token in the next (odd) frame.
- e) As soon as the IN packet is received and written to the receive FIFO, the OTG\_FS host generates an RXFLVL interrupt.
- f) In response to the RXFLVL interrupt, read the received packet status to determine the number of bytes received, then read the receive FIFO accordingly. The application must mask the RXFLVL interrupt before reading the receive FIFO, and unmask after reading the entire packet.
- g) The core generates the RXFLVL interrupt for the transfer completion status entry in the receive FIFO. The application must read and ignore the receive packet status when the receive packet status is not an IN data packet (PKTSTS in GRXSTSR ≠ 0b0010).
- h) The core generates an XFRC interrupt as soon as the receive packet status is read.
- i) In response to the XFRC interrupt, read the PKTCNT field in OTG\_FS\_HCTSIZ2. If the PKTCNT bit in OTG\_FS\_HCTSIZ2 is not equal to 0, disable the channel before re-initializing the channel for the next transfer, if any). If PKTCNT bit in

OTG\_FS\_HCTSIZ2 = 0, reinitialize the channel for the next transfer. This time, the application must reset the ODDFRM bit in OTG\_FS\_HCCHAR2.

- **Isochronous OUT transactions**

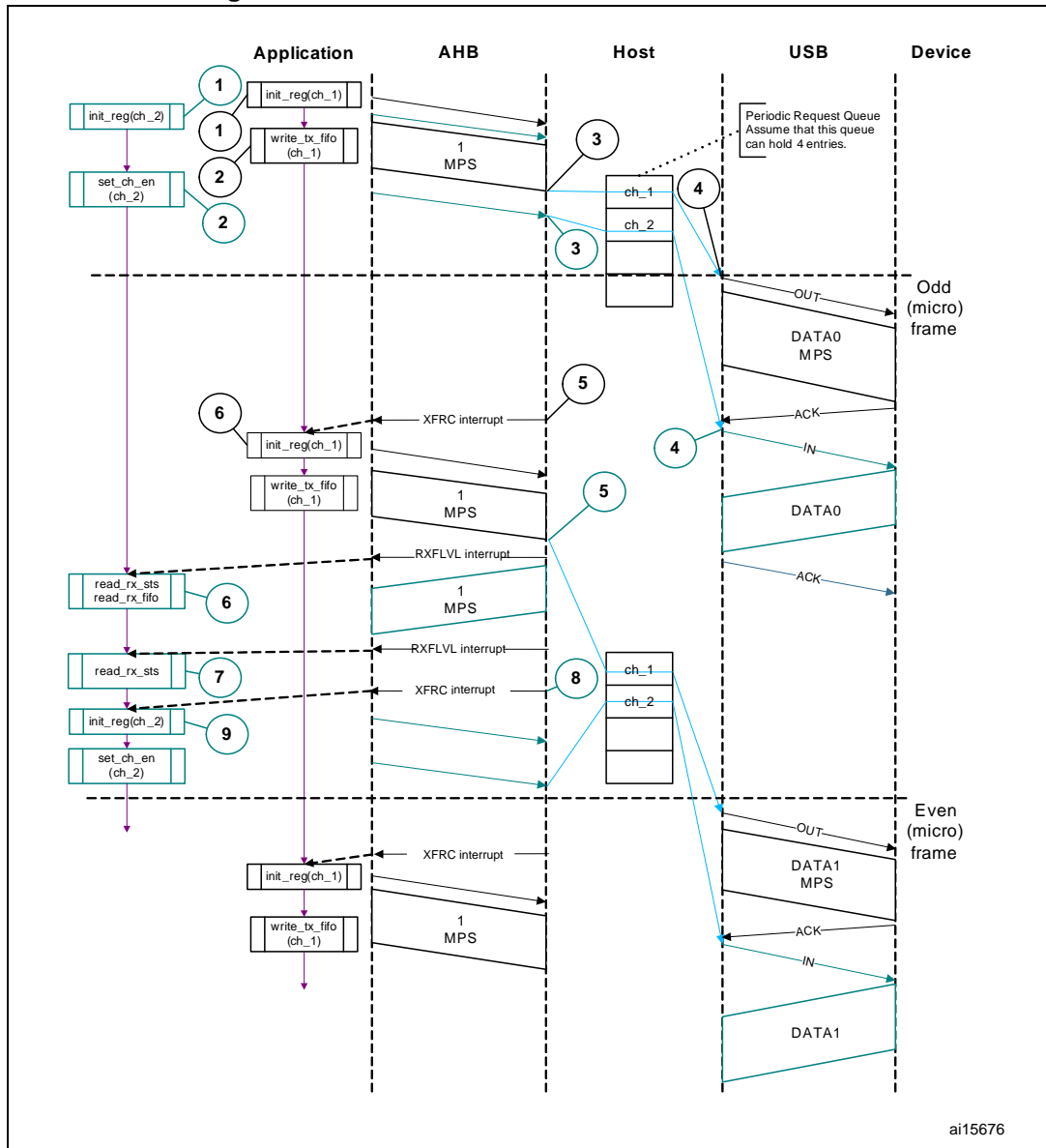
A typical isochronous OUT operation is shown in [Figure 257](#). The assumptions are:

- The application is attempting to send one packet every frame (up to 1 maximum packet size), starting with an odd frame. (transfer size = 1 024 bytes).
- The periodic transmit FIFO can hold one packet (1 KB).
- Periodic request queue depth = 4.

The sequence of operations is as follows:

- a) Initialize and enable channel 1. The application must set the ODDFRM bit in OTG\_FS\_HCCHAR1.
- b) Write the first packet for channel 1.
- c) Along with the last Word write of each packet, the OTG\_FS host writes an entry to the periodic request queue.
- d) The OTG\_FS host attempts to send the OUT token in the next frame (odd).
- e) The OTG\_FS host generates the XFRC interrupt as soon as the last packet is transmitted successfully.
- f) In response to the XFRC interrupt, reinitialize the channel for the next transfer.
- g) Handling non-ACK responses

Figure 257. Normal isochronous OUT/IN transactions



• Interrupt service routine for isochronous OUT/IN transactions

Code sample: Isochronous OUT

```

Unmask (FRMOR/XFRC)
if (XFRC)
{
    De-allocate Channel
}
else
    if (FRMOR)
    {
        Unmask CHH
        Disable Channel
    }
    
```

```
else
if (CHH)
{
Mask CHH
De-allocate Channel
}
Code sample: Isochronous IN
Unmask (TXERR/XFRC/FRMOR/BBERR)
if (XFRC or FRMOR)
{
if (XFRC and (OTG_FS_HCTSIZx.PKTCNT == 0))
{
Reset Error Count
De-allocate Channel
}
else
{
Unmask CHH
Disable Channel
}
}
else
if (TXERR or BBERR)
{
Increment Error Count
Unmask CHH
Disable Channel
}
else
if (CHH)
{
Mask CHH
if (Transfer Done or (Error_count == 3))
{
De-allocate Channel
}
else
{
Re-initialize Channel
}
}
}
```



- **Isochronous IN transactions**

The assumptions are:

- The application is attempting to receive one packet (up to 1 maximum packet size) in every frame starting with the next odd frame (transfer size = 1 024 bytes).
- The receive FIFO can hold at least one maximum-packet-size packet and two status Word per packet (1 031 bytes).
- Periodic request queue depth = 4.

The sequence of operations is as follows:

- a) Initialize channel 2. The application must set the ODDFRM bit in OTG\_FS\_HCCHAR2.
  - b) Set the CHENA bit in OTG\_FS\_HCCHAR2 to write an IN request to the periodic request queue.
  - c) The OTG\_FS host writes an IN request to the periodic request queue for each OTG\_FS\_HCCHAR2 register write with the CHENA bit set.
  - d) The OTG\_FS host attempts to send an IN token in the next odd frame.
  - e) As soon as the IN packet is received and written to the receive FIFO, the OTG\_FS host generates an RXFLVL interrupt.
  - f) In response to the RXFLVL interrupt, read the received packet status to determine the number of bytes received, then read the receive FIFO accordingly. The application must mask the RXFLVL interrupt before reading the receive FIFO, and unmask it after reading the entire packet.
  - g) The core generates an RXFLVL interrupt for the transfer completion status entry in the receive FIFO. This time, the application must read and ignore the receive packet status when the receive packet status is not an IN data packet (PKTSTS bit in OTG\_FS\_GRXSTSR  $\neq$  0b0010).
  - h) The core generates an XFRC interrupt as soon as the receive packet status is read.
  - i) In response to the XFRC interrupt, read the PKTCNT field in OTG\_FS\_HCTSIZ2. If  $PKTCNT \neq 0$  in OTG\_FS\_HCTSIZ2, disable the channel before re-initializing the channel for the next transfer, if any. If  $PKTCNT = 0$  in OTG\_FS\_HCTSIZ2, reinitialize the channel for the next transfer. This time, the application must reset the ODDFRM bit in OTG\_FS\_HCCHAR2.
- **Selecting the queue depth**

Choose the periodic and non-periodic request queue depths carefully to match the number of periodic/non-periodic endpoints accessed.

The non-periodic request queue depth affects the performance of non-periodic transfers. The deeper the queue (along with sufficient FIFO size), the more often the core is able to pipeline non-periodic transfers. If the queue size is small, the core is able to put in new requests only when the queue space is freed up.

The core's periodic request queue depth is critical to perform periodic transfers as scheduled. Select the periodic queue depth, based on the number of periodic transfers scheduled in a microframe. If the periodic request queue depth is smaller than the periodic transfers scheduled in a microframe, a frame overrun condition occurs.

- **Handling babble conditions**

OTG\_FS controller handles two cases of babble: packet babble and port babble.

Packet babble occurs if the device sends more data than the maximum packet size for

the channel. Port babble occurs if the core continues to receive data from the device at EOF2 (the end of frame 2, which is very close to SOF).

When OTG\_FS controller detects a packet babble, it stops writing data into the Rx buffer and waits for the end of packet (EOP). When it detects an EOP, it flushes already written data in the Rx buffer and generates a Babble interrupt to the application.

When OTG\_FS controller detects a port babble, it flushes the RxFIFO and disables the port. The core then generates a Port disabled interrupt (HPRTINT in OTG\_FS\_GINTSTS, PENCHNG in OTG\_FS\_HPRT). On receiving this interrupt, the application must determine that this is not due to an overcurrent condition (another cause of the Port Disabled interrupt) by checking POCA in OTG\_FS\_HPRT, then perform a soft reset. The core does not send any more tokens after it has detected a port babble condition.

## 22.17.5 Device programming model

### Endpoint initialization on USB reset

1. Set the NAK bit for all OUT endpoints
  - SNAK = 1 in OTG\_FS\_DOEPCTLx (for all OUT endpoints)
2. Unmask the following interrupt bits
  - INEP0 = 1 in OTG\_FS\_DAINMSK (control 0 IN endpoint)
  - OUTEP0 = 1 in OTG\_FS\_DAINMSK (control 0 OUT endpoint)
  - STUP = 1 in DOEPMSK
  - XFRC = 1 in DOEPMSK
  - XFRC = 1 in DIEPMSK
  - TOC = 1 in DIEPMSK
3. Set up the Data FIFO RAM for each of the FIFOs
  - Program the OTG\_FS\_GRXFSIZ register, to be able to receive control OUT data and setup data. If thresholding is not enabled, at a minimum, this must be equal to 1 max packet size of control endpoint 0 + 2 Words (for the status of the control OUT data packet) + 10 Words (for setup packets).
  - Program the OTG\_FS\_TX0FSIZ register (depending on the FIFO number chosen) to be able to transmit control IN data. At a minimum, this must be equal to 1 max packet size of control endpoint 0.
4. Program the following fields in the endpoint-specific registers for control OUT endpoint 0 to receive a SETUP packet
  - STUPCNT = 3 in OTG\_FS\_DOEPTSIZ0 (to receive up to 3 back-to-back SETUP packets)

At this point, all initialization required to receive SETUP packets is done.

### Endpoint initialization on enumeration completion

1. On the Enumeration Done interrupt (ENUMDNE in OTG\_FS\_GINTSTS), read the OTG\_FS\_DSTS register to determine the enumeration speed.
2. Program the MPSIZ field in OTG\_FS\_DIEPCTL0 to set the maximum packet size. This step configures control endpoint 0. The maximum packet size for a control endpoint depends on the enumeration speed.

At this point, the device is ready to receive SOF packets and is configured to perform control transfers on control endpoint 0.

### Endpoint initialization on SetAddress command

This section describes what the application must do when it receives a SetAddress command in a SETUP packet.

1. Program the OTG\_FS\_DCFG register with the device address received in the SetAddress command
1. Program the core to send out a status IN packet

### Endpoint initialization on SetConfiguration/SetInterface command

This section describes what the application must do when it receives a SetConfiguration or SetInterface command in a SETUP packet.

1. When a SetConfiguration command is received, the application must program the endpoint registers to configure them with the characteristics of the valid endpoints in the new configuration.
2. When a SetInterface command is received, the application must program the endpoint registers of the endpoints affected by this command.
3. Some endpoints that were active in the prior configuration or alternate setting are not valid in the new configuration or alternate setting. These invalid endpoints must be deactivated.
4. Unmask the interrupt for each active endpoint and mask the interrupts for all inactive endpoints in the OTG\_FS\_DAINMSK register.
5. Set up the Data FIFO RAM for each FIFO.
6. After all required endpoints are configured; the application must program the core to send a status IN packet.

At this point, the device core is configured to receive and transmit any type of data packet.

### Endpoint activation

This section describes the steps required to activate a device endpoint or to configure an existing device endpoint to a new type.

1. Program the characteristics of the required endpoint into the following fields of the OTG\_FS\_DIEPCTLx register (for IN or bidirectional endpoints) or the OTG\_FS\_DOEPCTLx register (for OUT or bidirectional endpoints).
  - Maximum packet size
  - USB active endpoint = 1
  - Endpoint start data toggle (for interrupt and bulk endpoints)
  - Endpoint type
  - TxFIFO number
2. Once the endpoint is activated, the core starts decoding the tokens addressed to that endpoint and sends out a valid handshake for each valid token received for the endpoint.

## Endpoint deactivation

This section describes the steps required to deactivate an existing endpoint.

1. In the endpoint to be deactivated, clear the USB active endpoint bit in the OTG\_FS\_DIEPCTLx register (for IN or bidirectional endpoints) or the OTG\_FS\_DOEPCTLx register (for OUT or bidirectional endpoints).
2. Once the endpoint is deactivated, the core ignores tokens addressed to that endpoint, which results in a timeout on the USB.

*Note:* The application must meet the following conditions to set up the device core to handle traffic:  
 NPTXFEM and RXFLVLM in the OTG\_FS\_GINTMSK register must be cleared.

## 22.17.6 Operational model

### SETUP and OUT data transfers

This section describes the internal data flow and application-level operations during data OUT transfers and SETUP transactions.

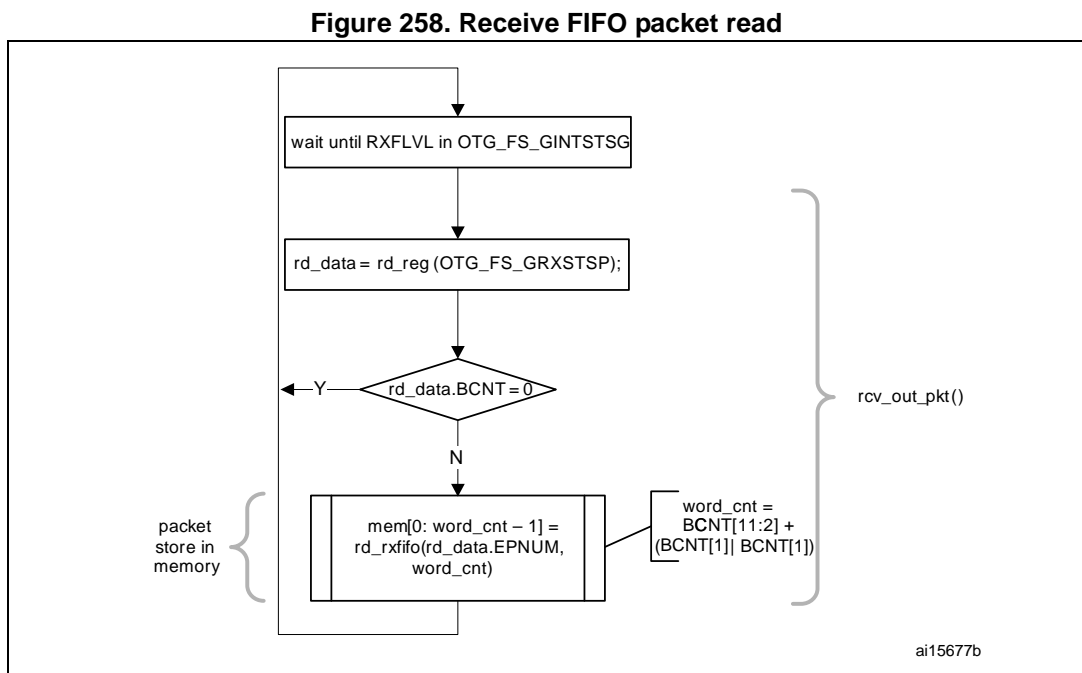
- **Packet read**

This section describes how to read packets (OUT data and SETUP packets) from the receive FIFO.

1. On catching an RXFLVL interrupt (OTG\_FS\_GINTSTS register), the application must read the Receive status pop register (OTG\_FS\_GRXSTSP).
2. The application can mask the RXFLVL interrupt (in OTG\_FS\_GINTSTS) by writing to RXFLVL = 0 (in OTG\_FS\_GINTMSK), until it has read the packet from the receive FIFO.
3. If the received packet's byte count is not 0, the byte count amount of data is popped from the receive Data FIFO and stored in memory. If the received packet byte count is 0, no data is popped from the receive data FIFO.
4. The receive FIFO's packet status readout indicates one of the following:
  - a) Global OUT NAK pattern:  
 PKTSTS = Global OUT NAK, BCNT = 0x000, EPNUM = Don't Care (0x0), DPID = Don't Care (0b00).  
 These data indicate that the global OUT NAK bit has taken effect.
  - b) SETUP packet pattern:  
 PKTSTS = SETUP, BCNT = 0x008, EPNUM = Control EP Num, DPID = D0.  
 These data indicate that a SETUP packet for the specified endpoint is now available for reading from the receive FIFO.
  - c) Setup stage done pattern:  
 PKTSTS = Setup Stage Done, BCNT = 0x0, EPNUM = Control EP Num, DPID = Don't Care (0b00).  
 These data indicate that the Setup stage for the specified endpoint has completed and the Data stage has started. After this entry is popped from the receive FIFO, the core asserts a Setup interrupt on the specified control OUT endpoint.
  - d) Data OUT packet pattern:  
 PKTSTS = DataOUT, BCNT = size of the received data OUT packet ( $0 \leq BCNT \leq 1024$ ), EPNUM = EPNUM on which the packet was received, DPID = Actual Data PID.

- e) Data transfer completed pattern:  
 PKTSTS = Data OUT Transfer Done, BCNT = 0x0, EPNUM = OUT EP Num on which the data transfer is complete, DPID = Don't Care (0b00).  
 These data indicate that an OUT data transfer for the specified OUT endpoint has completed. After this entry is popped from the receive FIFO, the core asserts a Transfer Completed interrupt on the specified OUT endpoint.
- 5. After the data payload is popped from the receive FIFO, the RXFLVL interrupt (OTG\_FS\_GINTSTS) must be unmasked.
- 6. Steps 1–5 are repeated every time the application detects assertion of the interrupt line due to RXFLVL in OTG\_FS\_GINTSTS. Reading an empty receive FIFO can result in undefined core behavior.

Figure 258 provides a flowchart of the above procedure.



• **SETUP transactions**

This section describes how the core handles SETUP packets and the application's sequence for handling SETUP transactions.

• **Application requirements**

1. To receive a SETUP packet, the STUPCNT field (OTG\_FS\_DOEPTSIZx) in a control OUT endpoint must be programmed to a non-zero value. When the application programs the STUPCNT field to a non-zero value, the core receives SETUP packets and writes them to the receive FIFO, irrespective of the NAK status and EPENA bit setting in OTG\_FS\_DOEPCTLx. The STUPCNT field is decremented every time the control endpoint receives a SETUP packet. If the STUPCNT field is not programmed to a proper value before receiving a SETUP packet, the core still receives the SETUP packet and decrements the STUPCNT field, but the application may not be able to

determine the correct number of SETUP packets received in the Setup stage of a control transfer.

- STUPCNT = 3 in OTG\_FS\_DOEPTSIZE
2. The application must always allocate some extra space in the Receive data FIFO, to be able to receive up to three SETUP packets on a control endpoint.
    - The space to be reserved is 10 Words. Three Words are required for the first SETUP packet, 1 Word is required for the Setup stage done Word and 6 Words are required to store two extra SETUP packets among all control endpoints.
    - 3 Words per SETUP packet are required to store 8 bytes of SETUP data and 4 bytes of SETUP status (Setup packet pattern). The core reserves this space in the receive data.
    - FIFO to write SETUP data only, and never uses this space for data packets.
  3. The application must read the 2 Words of the SETUP packet from the receive FIFO.
  4. The application must read and discard the Setup stage done Word from the receive FIFO.
- **Internal data flow**
5. When a SETUP packet is received, the core writes the received data to the receive FIFO, without checking for available space in the receive FIFO and irrespective of the endpoint's NAK and STALL bit settings.
    - The core internally sets the IN NAK and OUT NAK bits for the control IN/OUT endpoints on which the SETUP packet was received.
  6. For every SETUP packet received on the USB, 3 Words of data are written to the receive FIFO, and the STUPCNT field is decremented by 1.
    - The first Word contains control information used internally by the core
    - The second Word contains the first 4 bytes of the SETUP command
    - The third Word contains the last 4 bytes of the SETUP command
  7. When the Setup stage changes to a Data IN/OUT stage, the core writes an entry (Setup stage done Word) to the receive FIFO, indicating the completion of the Setup stage.
  8. On the AHB side, SETUP packets are emptied by the application.
  9. When the application pops the Setup stage done Word from the receive FIFO, the core interrupts the application with an STUP interrupt (OTG\_FS\_DOEPINTx), indicating it can process the received SETUP packet.
    - The core clears the endpoint enable bit for control OUT endpoints.
- **Application programming sequence**
1. Program the OTG\_FS\_DOEPTSIZE register.
    - STUPCNT = 3
  2. Wait for the RXFLVL interrupt (OTG\_FS\_GINTSTS) and empty the data packets from the receive FIFO.
  3. Assertion of the STUP interrupt (OTG\_FS\_DOEPINTx) marks a successful completion of the SETUP Data Transfer.
    - On this interrupt, the application must read the OTG\_FS\_DOEPTSIZE register to determine the number of SETUP packets received and process the last received SETUP packet.

Figure 259. Processing a SETUP packet



• **Handling more than three back-to-back SETUP packets**

Per the USB 2.0 specification, normally, during a SETUP packet error, a host does not send more than three back-to-back SETUP packets to the same endpoint. However, the USB 2.0 specification does not limit the number of back-to-back SETUP packets a host can send to the same endpoint. When this condition occurs, the OTG\_FS controller generates an interrupt (B2BSTUP in OTG\_FS\_DOEPINTx).

• **Setting the global OUT NAK**

**Internal data flow**

1. When the application sets the Global OUT NAK (SGONAK bit in OTG\_FS\_DCTL), the core stops writing data, except SETUP packets, to the receive FIFO. Irrespective of the space availability in the receive FIFO, non-isochronous OUT tokens receive a NAK handshake response, and the core ignores isochronous OUT data packets
2. The core writes the Global OUT NAK pattern to the receive FIFO. The application must reserve enough receive FIFO space to write this data pattern.
3. When the application pops the Global OUT NAK pattern Word from the receive FIFO, the core sets the GONAKEFF interrupt (OTG\_FS\_GINTSTS).
4. Once the application detects this interrupt, it can assume that the core is in Global OUT NAK mode. The application can clear this interrupt by clearing the SGONAK bit in OTG\_FS\_DCTL.

**Application programming sequence**

1. To stop receiving any kind of data in the receive FIFO, the application must set the Global OUT NAK bit by programming the following field:
  - SGONAK = 1 in OTG\_FS\_DCTL
2. Wait for the assertion of the GONAKEFF interrupt in OTG\_FS\_GINTSTS. When asserted, this interrupt indicates that the core has stopped receiving any type of data except SETUP packets.
3. The application can receive valid OUT packets after it has set SGONAK in OTG\_FS\_DCTL and before the core asserts the GONAKEFF interrupt (OTG\_FS\_GINTSTS).
4. The application can temporarily mask this interrupt by writing to the GINAKEFFM bit in the OTG\_FS\_GINTMSK register.
  - GINAKEFFM = 0 in the OTG\_FS\_GINTMSK register
5. Whenever the application is ready to exit the Global OUT NAK mode, it must clear the SGONAK bit in OTG\_FS\_DCTL. This also clears the GONAKEFF interrupt (OTG\_FS\_GINTSTS).
  - OTG\_FS\_DCTL = 1 in CGONAK
6. If the application has masked this interrupt earlier, it must be unmasked as follows:
  - GINAKEFFM = 1 in GINTMSK

- **Disabling an OUT endpoint**

The application must use this sequence to disable an OUT endpoint that it has enabled.

**Application programming sequence**

1. Before disabling any OUT endpoint, the application must enable Global OUT NAK mode in the core.
  - SGONAK = 1 in OTG\_FS\_DCTL
2. Wait for the GONAKEFF interrupt (OTG\_FS\_GINTSTS)
3. Disable the required OUT endpoint by programming the following fields:
  - EPDIS = 1 in OTG\_FS\_DOEPCTLx
  - SNAK = 1 in OTG\_FS\_DOEPCTLx
4. Wait for the EPDISD interrupt (OTG\_FS\_DOEPINTx), which indicates that the OUT endpoint is completely disabled. When the EPDISD interrupt is asserted, the core also clears the following bits:
  - EPDIS = 0 in OTG\_FS\_DOEPCTLx
  - EPENA = 0 in OTG\_FS\_DOEPCTLx
5. The application must clear the Global OUT NAK bit to start receiving data from other non-disabled OUT endpoints.
  - SGONAK = 0 in OTG\_FS\_DCTL

- **Generic non-isochronous OUT data transfers**

This section describes a regular non-isochronous OUT data transfer (control, bulk, or interrupt).

**Application requirements**

1. Before setting up an OUT transfer, the application must allocate a buffer in the memory to accommodate all data to be received as part of the OUT transfer.



2. For OUT transfers, the transfer size field in the endpoint's transfer size register must be a multiple of the maximum packet size of the endpoint, adjusted to the Word boundary.
  - $\text{transfer size}[\text{EPNUM}] = n \times (\text{MPSIZ}[\text{EPNUM}] + 4 - (\text{MPSIZ}[\text{EPNUM}] \bmod 4))$
  - $\text{packet count}[\text{EPNUM}] = n$
  - $n > 0$
3. On any OUT endpoint interrupt, the application must read the endpoint's transfer size register to calculate the size of the payload in the memory. The received payload size can be less than the programmed transfer size.
  - $\text{Payload size in memory} = \text{application programmed initial transfer size} - \text{core updated final transfer size}$
  - $\text{Number of USB packets in which this payload was received} = \text{application programmed initial packet count} - \text{core updated final packet count}$

#### Internal data flow

1. The application must set the transfer size and packet count fields in the endpoint-specific registers, clear the NAK bit, and enable the endpoint to receive the data.
2. Once the NAK bit is cleared, the core starts receiving data and writes it to the receive FIFO, as long as there is space in the receive FIFO. For every data packet received on the USB, the data packet and its status are written to the receive FIFO. Every packet (maximum packet size or short packet) written to the receive FIFO decrements the packet count field for that endpoint by 1.
  - OUT data packets received with bad data CRC are flushed from the receive FIFO automatically.
  - After sending an ACK for the packet on the USB, the core discards non-isochronous OUT data packets that the host, which cannot detect the ACK, re-sends. The application does not detect multiple back-to-back data OUT packets on the same endpoint with the same data PID. In this case the packet count is not decremented.
  - If there is no space in the receive FIFO, isochronous or non-isochronous data packets are ignored and not written to the receive FIFO. Additionally, non-isochronous OUT tokens receive a NAK handshake reply.
  - In all the above three cases, the packet count is not decremented because no data are written to the receive FIFO.
3. When the packet count becomes 0 or when a short packet is received on the endpoint, the NAK bit for that endpoint is set. Once the NAK bit is set, the isochronous or non-isochronous data packets are ignored and not written to the receive FIFO, and non-isochronous OUT tokens receive a NAK handshake reply.
4. After the data are written to the receive FIFO, the application reads the data from the receive FIFO and writes it to external memory, one packet at a time per endpoint.
5. At the end of every packet write on the AHB to external memory, the transfer size for the endpoint is decremented by the size of the written packet.
6. The OUT data transfer completed pattern for an OUT endpoint is written to the receive FIFO on one of the following conditions:
  - The transfer size is 0 and the packet count is 0
  - The last OUT data packet written to the receive FIFO is a short packet ( $0 \leq \text{packet size} < \text{maximum packet size}$ )
7. When either the application pops this entry (OUT data transfer completed), a transfer completed interrupt is generated for the endpoint and the endpoint enable is cleared.

### Application programming sequence

1. Program the OTG\_FS\_DOEPTSIZx register for the transfer size and the corresponding packet count.
2. Program the OTG\_FS\_DOEPCTLx register with the endpoint characteristics, and set the EPENA and CNAK bits.
  - EPENA = 1 in OTG\_FS\_DOEPCTLx
  - CNAK = 1 in OTG\_FS\_DOEPCTLx
3. Wait for the RXFLVL interrupt (in OTG\_FS\_GINTSTS) and empty the data packets from the receive FIFO.
  - This step can be repeated many times, depending on the transfer size.
4. Asserting the XFRC interrupt (OTG\_FS\_DOEPINTx) marks a successful completion of the non-isochronous OUT data transfer.
5. Read the OTG\_FS\_DOEPTSIZx register to determine the size of the received data payload.

- **Generic isochronous OUT data transfer**

This section describes a regular isochronous OUT data transfer.

### Application requirements

1. All the application requirements for non-isochronous OUT data transfers also apply to isochronous OUT data transfers.
2. For isochronous OUT data transfers, the transfer size and packet count fields must always be set to the number of maximum-packet-size packets that can be received in a single frame and no more. Isochronous OUT data transfers cannot span more than 1 frame.
3. The application must read all isochronous OUT data packets from the receive FIFO (data and status) before the end of the periodic frame (EOPF interrupt in OTG\_FS\_GINTSTS).
4. To receive data in the following frame, an isochronous OUT endpoint must be enabled after the EOPF (OTG\_FS\_GINTSTS) and before the SOF (OTG\_FS\_GINTSTS).

### Internal data flow

1. The internal data flow for isochronous OUT endpoints is the same as that for non-isochronous OUT endpoints, but for a few differences.
2. When an isochronous OUT endpoint is enabled by setting the Endpoint Enable and clearing the NAK bits, the Even/Odd frame bit must also be set appropriately. The core receives data on an isochronous OUT endpoint in a particular frame only if the following condition is met:
  - EONUM (in OTG\_FS\_DOEPCTLx) = SOFFN[0] (in OTG\_FS\_DSTS)
3. When the application completely reads an isochronous OUT data packet (data and status) from the receive FIFO, the core updates the RXDPID field in OTG\_FS\_DOEPTSIZx with the data PID of the last isochronous OUT data packet read from the receive FIFO.

**Application programming sequence**

1. Program the OTG\_FS\_DOEPTSIZx register for the transfer size and the corresponding packet count
2. Program the OTG\_FS\_DOEPCTLx register with the endpoint characteristics and set the Endpoint Enable, ClearNAK, and Even/Odd frame bits.
  - EPENA = 1
  - CNAK = 1
  - EONUM = (0: Even/1: Odd)
3. Wait for the RXFLVL interrupt (in OTG\_FS\_GINTSTS) and empty the data packets from the receive FIFO
  - This step can be repeated many times, depending on the transfer size.
4. The assertion of the XFRC interrupt (in OTG\_FS\_DOEPINTx) marks the completion of the isochronous OUT data transfer. This interrupt does not necessarily mean that the data in memory are good.
5. This interrupt cannot always be detected for isochronous OUT transfers. Instead, the application can detect the IISOOXFRM interrupt in OTG\_FS\_GINTSTS.
6. Read the OTG\_FS\_DOEPTSIZx register to determine the size of the received transfer and to determine the validity of the data received in the frame. The application must treat the data received in memory as valid only if one of the following conditions is met:
  - RXDPID = D0 (in OTG\_FS\_DOEPTSIZx) and the number of USB packets in which this payload was received = 1
  - RXDPID = D1 (in OTG\_FS\_DOEPTSIZx) and the number of USB packets in which this payload was received = 2
  - RXDPID = D2 (in OTG\_FS\_DOEPTSIZx) and the number of USB packets in which this payload was received = 3The number of USB packets in which this payload was received =  
Application programmed initial packet count – Core updated final packet count

The application can discard invalid data packets.

**• Incomplete isochronous OUT data transfers**

This section describes the application programming sequence when isochronous OUT data packets are dropped inside the core.

**Internal data flow**

1. For isochronous OUT endpoints, the XFRC interrupt (in OTG\_FS\_DOEPINTx) may not always be asserted. If the core drops isochronous OUT data packets, the application could fail to detect the XFRC interrupt (OTG\_FS\_DOEPINTx) under the following circumstances:
  - When the receive FIFO cannot accommodate the complete ISO OUT data packet, the core drops the received ISO OUT data
  - When the isochronous OUT data packet is received with CRC errors
  - When the isochronous OUT token received by the core is corrupted
  - When the application is very slow in reading the data from the receive FIFO
2. When the core detects an end of periodic frame before transfer completion to all isochronous OUT endpoints, it asserts the incomplete Isochronous OUT data interrupt (IISOOXFRM in OTG\_FS\_GINTSTS), indicating that an XFRC interrupt (in OTG\_FS\_DOEPINTx) is not asserted on at least one of the isochronous OUT

endpoints. At this point, the endpoint with the incomplete transfer remains enabled, but no active transfers remain in progress on this endpoint on the USB.

#### Application programming sequence

1. Asserting the IISOXFRM interrupt (OTG\_FS\_GINTSTS) indicates that in the current frame, at least one isochronous OUT endpoint has an incomplete transfer.
2. If this occurs because isochronous OUT data is not completely emptied from the endpoint, the application must ensure that the application empties all isochronous OUT data (data and status) from the receive FIFO before proceeding.
  - When all data are emptied from the receive FIFO, the application can detect the XFRC interrupt (OTG\_FS\_DOEPINTx). In this case, the application must re-enable the endpoint to receive isochronous OUT data in the next frame.
3. When it receives an IISOXFRM interrupt (in OTG\_FS\_GINTSTS), the application must read the control registers of all isochronous OUT endpoints (OTG\_FS\_DOEPCTLx) to determine which endpoints had an incomplete transfer in the current microframe. An endpoint transfer is incomplete if both the following conditions are met:
  - EONUM bit (in OTG\_FS\_DOEPCTLx) = SOFFN[0] (in OTG\_FS\_DSTS)
  - EPENA = 1 (in OTG\_FS\_DOEPCTLx)
4. The previous step must be performed before the SOF interrupt (in OTG\_FS\_GINTSTS) is detected, to ensure that the current frame number is not changed.
5. For isochronous OUT endpoints with incomplete transfers, the application must discard the data in the memory and disable the endpoint by setting the EPDIS bit in OTG\_FS\_DOEPCTLx.
6. Wait for the EPDIS interrupt (in OTG\_FS\_DOEPINTx) and enable the endpoint to receive new data in the next frame.
  - Because the core can take some time to disable the endpoint, the application may not be able to receive the data in the next frame after receiving bad isochronous data.

- **Stalling a non-isochronous OUT endpoint**

This section describes how the application can stall a non-isochronous endpoint.

1. Put the core in the Global OUT NAK mode.
2. Disable the required endpoint
  - When disabling the endpoint, instead of setting the SNAK bit in OTG\_FS\_DOEPCTL, set STALL = 1 (in OTG\_FS\_DOEPCTL).  
The STALL bit always takes precedence over the NAK bit.
3. When the application is ready to end the STALL handshake for the endpoint, the STALL bit (in OTG\_FS\_DOEPCTLx) must be cleared.
4. If the application is setting or clearing a STALL for an endpoint due to a SetFeature.Endpoint Halt or ClearFeature.Endpoint Halt command, the STALL bit must be set or cleared before the application sets up the Status stage transfer on the control endpoint.

#### Examples

This section describes and depicts some fundamental transfer types and scenarios.

- Bulk OUT transaction



- In polling mode, the application monitors the status of the endpoint transmit data FIFO by reading the OTG\_FS\_DTXFSTSx register, to determine if there is enough space in the data FIFO.
  - In interrupt mode, the application waits for the TXFE interrupt (in OTG\_FS\_DIEPINTx) and then reads the OTG\_FS\_DTXFSTSx register, to determine if there is enough space in the data FIFO.
  - To write a single non-zero length data packet, there must be space to write the entire packet in the data FIFO.
  - To write zero length packet, the application must not look at the FIFO space.
2. Using one of the above mentioned methods, when the application determines that there is enough space to write a transmit packet, the application must first write into the endpoint control register, before writing the data into the data FIFO. Typically, the application, must do a read modify write on the OTG\_FS\_DIEPCTLx register to avoid modifying the contents of the register, except for setting the Endpoint Enable bit.

The application can write multiple packets for the same endpoint into the transmit FIFO, if space is available. For periodic IN endpoints, the application must write packets only for one microframe. It can write packets for the next periodic transaction only after getting transfer complete for the previous transaction.

- **Setting IN endpoint NAK**

#### Internal data flow

1. When the application sets the IN NAK for a particular endpoint, the core stops transmitting data on the endpoint, irrespective of data availability in the endpoint's transmit FIFO.
2. Non-isochronous IN tokens receive a NAK handshake reply
  - Isochronous IN tokens receive a zero-data-length packet reply
3. The core asserts the INEPNE (IN endpoint NAK effective) interrupt in OTG\_FS\_DIEPINTx in response to the SNAK bit in OTG\_FS\_DIEPCTLx.
4. Once this interrupt is seen by the application, the application can assume that the endpoint is in IN NAK mode. This interrupt can be cleared by the application by setting the CNAK bit in OTG\_FS\_DIEPCTLx.

#### Application programming sequence

1. To stop transmitting any data on a particular IN endpoint, the application must set the IN NAK bit. To set this bit, the following field must be programmed.
  - SNAK = 1 in OTG\_FS\_DIEPCTLx
2. Wait for assertion of the INEPNE interrupt in OTG\_FS\_DIEPINTx. This interrupt indicates that the core has stopped transmitting data on the endpoint.
3. The core can transmit valid IN data on the endpoint after the application has set the NAK bit, but before the assertion of the NAK Effective interrupt.
4. The application can mask this interrupt temporarily by writing to the INEPNEM bit in DIEPMSK.
  - INEPNEM = 0 in DIEPMSK
5. To exit Endpoint NAK mode, the application must clear the NAK status bit (NAKSTS) in OTG\_FS\_DIEPCTLx. This also clears the INEPNE interrupt (in OTG\_FS\_DIEPINTx).
  - CNAK = 1 in OTG\_FS\_DIEPCTLx
6. If the application masked this interrupt earlier, it must be unmasked as follows:

- INEPNEM = 1 in DIEPMSK

- **IN endpoint disable**

Use the following sequence to disable a specific IN endpoint that has been previously enabled.

**Application programming sequence**

1. The application must stop writing data on the AHB for the IN endpoint to be disabled.
2. The application must set the endpoint in NAK mode.
  - SNAK = 1 in OTG\_FS\_DIEPCTLx
3. Wait for the INEPNE interrupt in OTG\_FS\_DIEPINTx.
4. Set the following bits in the OTG\_FS\_DIEPCTLx register for the endpoint that must be disabled.
  - EPDIS = 1 in OTG\_FS\_DIEPCTLx
  - SNAK = 1 in OTG\_FS\_DIEPCTLx
5. Assertion of the EPDISD interrupt in OTG\_FS\_DIEPINTx indicates that the core has completely disabled the specified endpoint. Along with the assertion of the interrupt, the core also clears the following bits:
  - EPENA = 0 in OTG\_FS\_DIEPCTLx
  - EPDIS = 0 in OTG\_FS\_DIEPCTLx
6. The application must read the OTG\_FS\_DIEPTSIZx register for the periodic IN EP, to calculate how much data on the endpoint were transmitted on the USB.
7. The application must flush the data in the Endpoint transmit FIFO, by setting the following fields in the OTG\_FS\_GRSTCTL register:
  - TXFNUM (in OTG\_FS\_GRSTCTL) = Endpoint transmit FIFO number
  - TXFFLSH in (OTG\_FS\_GRSTCTL) = 1

The application must poll the OTG\_FS\_GRSTCTL register, until the TXFFLSH bit is cleared by the core, which indicates the end of flush operation. To transmit new data on this endpoint, the application can re-enable the endpoint at a later point.

- **Generic non-periodic IN data transfers**

**Application requirements**

1. Before setting up an IN transfer, the application must ensure that all data to be transmitted as part of the IN transfer are part of a single buffer.
2. For IN transfers, the Transfer Size field in the Endpoint Transfer Size register denotes a payload that constitutes multiple maximum-packet-size packets and a single short packet. This short packet is transmitted at the end of the transfer.
  - To transmit a few maximum-packet-size packets and a short packet at the end of the transfer:  

$$\text{Transfer size[EPNUM]} = x \times \text{MPSIZ[EPNUM]} + \text{sp}$$
 If  $(\text{sp} > 0)$ , then  $\text{packet count[EPNUM]} = x + 1$ .  
 Otherwise,  $\text{packet count[EPNUM]} = x$
  - To transmit a single zero-length data packet:  

$$\text{Transfer size[EPNUM]} = 0$$

$$\text{Packet count[EPNUM]} = 1$$
  - To transmit a few maximum-packet-size packets and a zero-length data packet at the end of the transfer, the application must split the transfer into two parts. The first sends maximum-packet-size data packets and the second sends the zero-length data packet alone.  
 First transfer:  $\text{transfer size[EPNUM]} = x \times \text{MPSIZ[epnum]}$ ;  $\text{packet count} = n$ ;  
 Second transfer:  $\text{transfer size[EPNUM]} = 0$ ;  $\text{packet count} = 1$ ;
3. Once an endpoint is enabled for data transfers, the core updates the Transfer size register. At the end of the IN transfer, the application must read the Transfer size register to determine how much data posted in the transmit FIFO have already been sent on the USB.
4. Data fetched into transmit FIFO = Application-programmed initial transfer size – core-updated final transfer size
  - Data transmitted on USB = (application-programmed initial packet count – Core updated final packet count)  $\times$  MPSIZ[EPNUM]
  - Data yet to be transmitted on USB = (Application-programmed initial transfer size – data transmitted on USB)

**Internal data flow**

1. The application must set the transfer size and packet count fields in the endpoint-specific registers and enable the endpoint to transmit the data.
2. The application must also write the required data to the transmit FIFO for the endpoint.
3. Every time a packet is written into the transmit FIFO by the application, the transfer size for that endpoint is decremented by the packet size. The data is fetched from the memory by the application, until the transfer size for the endpoint becomes 0. After writing the data into the FIFO, the “number of packets in FIFO” count is incremented (this is a 3-bit count, internally maintained by the core for each IN endpoint transmit FIFO. The maximum number of packets maintained by the core at any time in an IN endpoint FIFO is eight). For zero-length packets, a separate flag is set for each FIFO, without any data in the FIFO.
4. Once the data are written to the transmit FIFO, the core reads them out upon receiving an IN token. For every non-isochronous IN data packet transmitted with an ACK



- handshake, the packet count for the endpoint is decremented by one, until the packet count is zero. The packet count is not decremented on a timeout.
5. For zero length packets (indicated by an internal zero length flag), the core sends out a zero-length packet for the IN token and decrements the packet count field.
  6. If there are no data in the FIFO for a received IN token and the packet count field for that endpoint is zero, the core generates an "IN token received when TxFIFO is empty" (ITTXFE) Interrupt for the endpoint, provided that the endpoint NAK bit is not set. The core responds with a NAK handshake for non-isochronous endpoints on the USB.
  7. The core internally rewinds the FIFO pointers and no timeout interrupt is generated.
  8. When the transfer size is 0 and the packet count is 0, the transfer complete (XFRC) interrupt for the endpoint is generated and the endpoint enable is cleared.

#### Application programming sequence

1. Program the OTG\_FS\_DIEPTSIZx register with the transfer size and corresponding packet count.
2. Program the OTG\_FS\_DIEPCTLx register with the endpoint characteristics and set the CNAK and EPENA (Endpoint Enable) bits.
3. When transmitting non-zero length data packet, the application must poll the OTG\_FS\_DTXFSTSx register (where x is the FIFO number associated with that endpoint) to determine whether there is enough space in the data FIFO. The application can optionally use TXFE (in OTG\_FS\_DIEPINTx) before writing the data.

#### • Generic periodic IN data transfers

This section describes a typical periodic IN data transfer.

#### Application requirements

1. Application requirements 1, 2, 3, and 4 of [Generic non-periodic IN data transfers on page 787](#) also apply to periodic IN data transfers, except for a slight modification of requirement 2.
  - The application can only transmit multiples of maximum-packet-size data packets or multiples of maximum-packet-size packets, plus a short packet at the end. To transmit a few maximum-packet-size packets and a short packet at the end of the transfer, the following conditions must be met:
 
$$\text{transfer size}[\text{EPNUM}] = x \times \text{MPSIZ}[\text{EPNUM}] + \text{sp}$$
 (where x is an integer  $\geq 0$ , and  $0 \leq \text{sp} < \text{MPSIZ}[\text{EPNUM}]$ )
 
$$\text{If } (\text{sp} > 0), \text{ packet count}[\text{EPNUM}] = x + 1$$
 Otherwise,  $\text{packet count}[\text{EPNUM}] = x$ ;
 
$$\text{MCNT}[\text{EPNUM}] = \text{packet count}[\text{EPNUM}]$$
  - The application cannot transmit a zero-length data packet at the end of a transfer. It can transmit a single zero-length data packet by itself. To transmit a single zero-length data packet:
 
$$\text{transfer size}[\text{EPNUM}] = 0$$

$$\text{packet count}[\text{EPNUM}] = 1$$

$$\text{MCNT}[\text{EPNUM}] = \text{packet count}[\text{EPNUM}]$$
2. The application can only schedule data transfers one frame at a time.
  - $(\text{MCNT} - 1) \times \text{MPSIZ} \leq \text{XFERSIZ} \leq \text{MCNT} \times \text{MPSIZ}$
  - $\text{PKTCNT} = \text{MCNT}$  (in OTG\_FS\_DIEPTSIZx)

- If  $XFERSIZ < MCNT \times MPSIZ$ , the last data packet of the transfer is a short packet.
  - Note that: MCNT is in OTG\_FS\_DIEPTISZx, MPSIZ is in OTG\_FS\_DIEPCTLx, PKTCNT is in OTG\_FS\_DIEPTISZx and XFERSIZ is in OTG\_FS\_DIEPTISZx
3. The complete data to be transmitted in the frame must be written into the transmit FIFO by the application, before the IN token is received. Even when 1 Word of the data to be transmitted per frame is missing in the transmit FIFO when the IN token is received, the core behaves as when the FIFO is empty. When the transmit FIFO is empty:
    - A zero data length packet would be transmitted on the USB for isochronous IN endpoints
    - A NAK handshake would be transmitted on the USB for interrupt IN endpoints

#### Internal data flow

1. The application must set the transfer size and packet count fields in the endpoint-specific registers and enable the endpoint to transmit the data.
2. The application must also write the required data to the associated transmit FIFO for the endpoint.
3. Every time the application writes a packet to the transmit FIFO, the transfer size for that endpoint is decremented by the packet size. The data are fetched from application memory until the transfer size for the endpoint becomes 0.
4. When an IN token is received for a periodic endpoint, the core transmits the data in the FIFO, if available. If the complete data payload (complete packet, in dedicated FIFO mode) for the frame is not present in the FIFO, then the core generates an IN token received when TxFIFO empty interrupt for the endpoint.
  - A zero-length data packet is transmitted on the USB for isochronous IN endpoints
  - A NAK handshake is transmitted on the USB for interrupt IN endpoints
5. The packet count for the endpoint is decremented by 1 under the following conditions:
  - For isochronous endpoints, when a zero- or non-zero-length data packet is transmitted
  - For interrupt endpoints, when an ACK handshake is transmitted
  - When the transfer size and packet count are both 0, the transfer completed interrupt for the endpoint is generated and the endpoint enable is cleared.
6. At the “Periodic frame Interval” (controlled by PFIVL in OTG\_FS\_DCFG), when the core finds non-empty any of the isochronous IN endpoint FIFOs scheduled for the current frame non-empty, the core generates an IISOIXFR interrupt in OTG\_FS\_GINTSTS.

#### Application programming sequence

1. Program the OTG\_FS\_DIEPCTLx register with the endpoint characteristics and set the CNAK and EPENA bits.
2. Write the data to be transmitted in the next frame to the transmit FIFO.
3. Asserting the ITTXFE interrupt (in OTG\_FS\_DIEPINTx) indicates that the application has not yet written all data to be transmitted to the transmit FIFO.
4. If the interrupt endpoint is already enabled when this interrupt is detected, ignore the interrupt. If it is not enabled, enable the endpoint so that the data can be transmitted on the next IN token attempt.
5. Asserting the XFRC interrupt (in OTG\_FS\_DIEPINTx) with no ITTXFE interrupt in OTG\_FS\_DIEPINTx indicates the successful completion of an isochronous IN transfer.

A read to the OTG\_FS\_DIEPTSIZx register must give transfer size = 0 and packet count = 0, indicating all data were transmitted on the USB.

6. Asserting the XFRC interrupt (in OTG\_FS\_DIEPINTx), with or without the ITTXFE interrupt (in OTG\_FS\_DIEPINTx), indicates the successful completion of an interrupt IN transfer. A read to the OTG\_FS\_DIEPTSIZx register must give transfer size = 0 and packet count = 0, indicating all data were transmitted on the USB.
7. Asserting the incomplete isochronous IN transfer (IISOIXFR) interrupt in OTG\_FS\_GINTSTS with none of the aforementioned interrupts indicates the core did not receive at least 1 periodic IN token in the current frame.

- **Incomplete isochronous IN data transfers**

This section describes what the application must do on an incomplete isochronous IN data transfer.

#### Internal data flow

1. An isochronous IN transfer is treated as incomplete in one of the following conditions:
  - a) The core receives a corrupted isochronous IN token on at least one isochronous IN endpoint. In this case, the application detects an incomplete isochronous IN transfer interrupt (IISOIXFR in OTG\_FS\_GINTSTS).
  - b) The application is slow to write the complete data payload to the transmit FIFO and an IN token is received before the complete data payload is written to the FIFO. In this case, the application detects an IN token received when Tx FIFO empty interrupt in OTG\_FS\_DIEPINTx. The application can ignore this interrupt, as it eventually results in an incomplete isochronous IN transfer interrupt (IISOIXFR in OTG\_FS\_GINTSTS) at the end of periodic frame.  
The core transmits a zero-length data packet on the USB in response to the received IN token.
2. The application must stop writing the data payload to the transmit FIFO as soon as possible.
3. The application must set the NAK bit and the disable bit for the endpoint.
4. The core disables the endpoint, clears the disable bit, and asserts the Endpoint Disable interrupt for the endpoint.

#### Application programming sequence

1. The application can ignore the IN token received when Tx FIFO empty interrupt in OTG\_FS\_DIEPINTx on any isochronous IN endpoint, as it eventually results in an incomplete isochronous IN transfer interrupt (in OTG\_FS\_GINTSTS).
2. Assertion of the incomplete isochronous IN transfer interrupt (in OTG\_FS\_GINTSTS) indicates an incomplete isochronous IN transfer on at least one of the isochronous IN endpoints.
3. The application must read the Endpoint Control register for all isochronous IN endpoints to detect endpoints with incomplete IN data transfers.
4. The application must stop writing data to the Periodic Transmit FIFOs associated with these endpoints on the AHB.
5. Program the following fields in the OTG\_FS\_DIEPCTLx register to disable the endpoint:
  - SNAK = 1 in OTG\_FS\_DIEPCTLx
  - EPDIS = 1 in OTG\_FS\_DIEPCTLx

6. The assertion of the Endpoint Disabled interrupt in OTG\_FS\_DIEPINTx indicates that the core has disabled the endpoint.
  - At this point, the application must flush the data in the associated transmit FIFO or overwrite the existing data in the FIFO by enabling the endpoint for a new transfer in the next microframe. To flush the data, the application must use the OTG\_FS\_GRSTCTL register.
- **Stalling non-isochronous IN endpoints**

This section describes how the application can stall a non-isochronous endpoint.

#### Application programming sequence

1. Disable the IN endpoint to be stalled. Set the STALL bit as well.
2. EPDIS = 1 in OTG\_FS\_DIEPCTLx, when the endpoint is already enabled
  - STALL = 1 in OTG\_FS\_DIEPCTLx
  - The STALL bit always takes precedence over the NAK bit
3. Assertion of the Endpoint Disabled interrupt (in OTG\_FS\_DIEPINTx) indicates to the application that the core has disabled the specified endpoint.
4. The application must flush the non-periodic or periodic transmit FIFO, depending on the endpoint type. In case of a non-periodic endpoint, the application must re-enable the other non-periodic endpoints that do not need to be stalled, to transmit data.
5. Whenever the application is ready to end the STALL handshake for the endpoint, the STALL bit must be cleared in OTG\_FS\_DIEPCTLx.
6. If the application sets or clears a STALL bit for an endpoint due to a SetFeature.Endpoint Halt command or ClearFeature.Endpoint Halt command, the STALL bit must be set or cleared before the application sets up the Status stage transfer on the control endpoint.

#### Special case: stalling the control OUT endpoint

The core must stall IN/OUT tokens if, during the data stage of a control transfer, the host sends more IN/OUT tokens than are specified in the SETUP packet. In this case, the application must enable the ITTXFE interrupt in OTG\_FS\_DIEPINTx and the OTEPDIS interrupt in OTG\_FS\_DOEPINTx during the data stage of the control transfer, after the core has transferred the amount of data specified in the SETUP packet. Then, when the application receives this interrupt, it must set the STALL bit in the corresponding endpoint control register, and clear this interrupt.

### 22.17.7 Worst case response time

When the OTG\_FS controller acts as a device, there is a worst case response time for any tokens that follow an isochronous OUT. This worst case response time depends on the AHB clock frequency.

The core registers are in the AHB domain, and the core does not accept another token before updating these register values. The worst case is for any token following an isochronous OUT, because for an isochronous transaction, there is no handshake and the next token could come sooner. This worst case value is 7 PHY clocks when the AHB clock is the same as the PHY clock. When the AHB clock is faster, this value is smaller.

If this worst case condition occurs, the core responds to bulk/interrupt tokens with a NAK and drops isochronous and SETUP tokens. The host interprets this as a timeout condition for SETUP and retries the SETUP packet. For isochronous transfers, the Incomplete isochronous IN transfer interrupt (IISOIXFR) and Incomplete isochronous OUT transfer

interrupt (IISOOXFR) inform the application that isochronous IN/OUT packets were dropped.

### Choosing the value of TRDT in OTG\_FS\_GUSBCFG

The value in TRDT (OTG\_FS\_GUSBCFG) is the time it takes for the MAC, in terms of PHY clocks after it has received an IN token, to get the FIFO status, and thus the first data from the PFC block. This time involves the synchronization delay between the PHY and AHB clocks. The worst case delay for this is when the AHB clock is the same as the PHY clock. In this case, the delay is 5 clocks.

Once the MAC receives an IN token, this information (token received) is synchronized to the AHB clock by the PFC (the PFC runs on the AHB clock). The PFC then reads the data from the SPRAM and writes them into the dual clock source buffer. The MAC then reads the data out of the source buffer (4 deep).

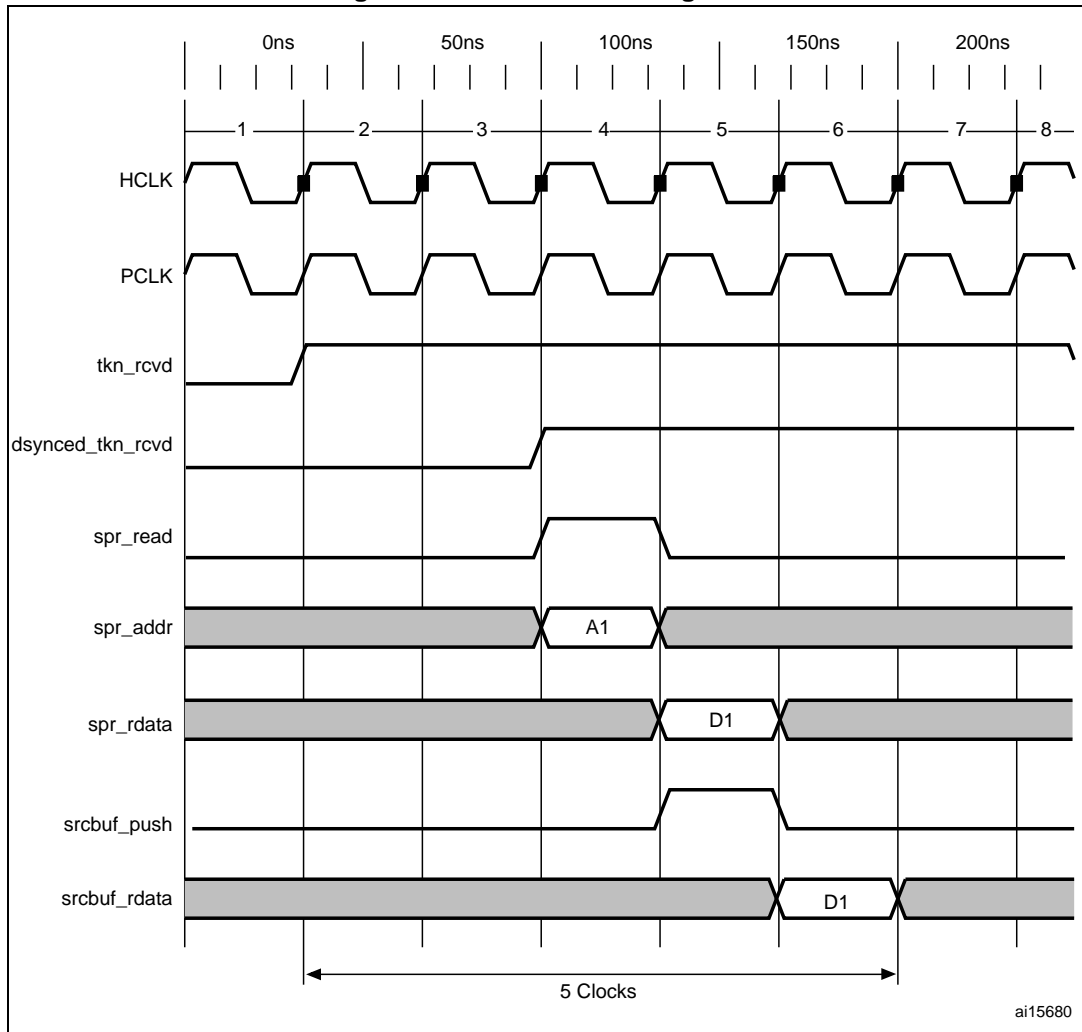
If the AHB is running at a higher frequency than the PHY, the application can use a smaller value for TRDT (in OTG\_FS\_GUSBCFG).

[Figure 261](#) has the following signals:

- `tkn_rcvd`: Token received information from MAC to PFC
- `dynced_tkn_rcvd`: Doubled sync `tkn_rcvd`, from PCLK to HCLK domain
- `spr_read`: Read to SPRAM
- `spr_addr`: Address to SPRAM
- `spr_rdata`: Read data from SPRAM
- `srcbuf_push`: Push to the source buffer
- `srcbuf_rdata`: Read data from the source buffer. Data seen by MAC

Refer to [Table 131: TRDT values](#) for the values of TRDT versus AHB clock frequency.

Figure 261. TRDT max timing case



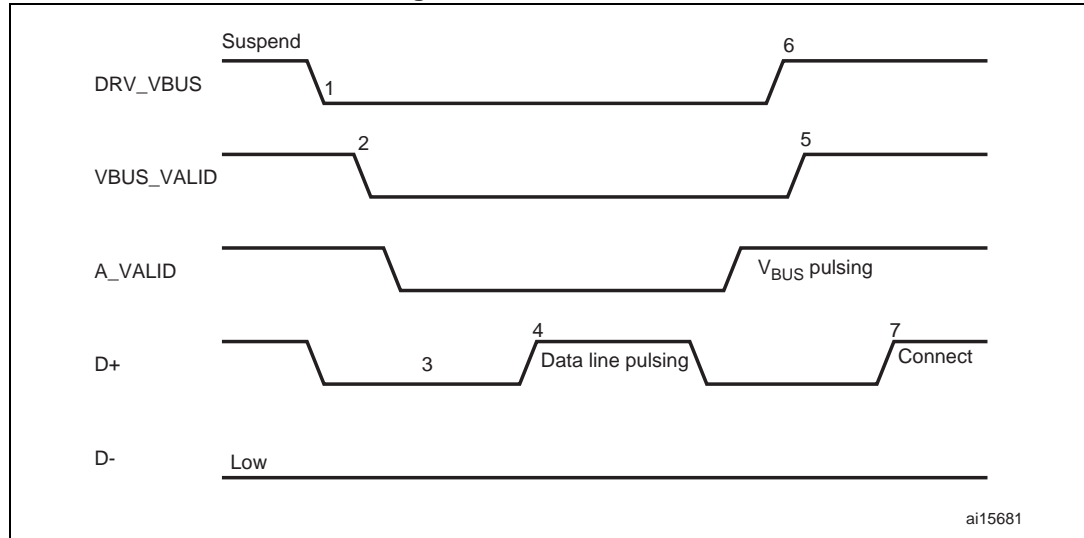
### 22.17.8 OTG programming model

The OTG\_FS controller is an OTG device supporting HNP and SRP. When the core is connected to an “A” plug, it is referred to as an A-device. When the core is connected to a “B” plug it is referred to as a B-device. In host mode, the OTG\_FS controller turns off  $V_{BUS}$  to conserve power. SRP is a method by which the B-device signals the A-device to turn on  $V_{BUS}$  power. A device must perform both data-line pulsing and  $V_{BUS}$  pulsing, but a host can detect either data-line pulsing or  $V_{BUS}$  pulsing for SRP. HNP is a method by which the B-device negotiates and switches to host role. In Negotiated mode after HNP, the B-device suspends the bus and reverts to the device role.

**A-device session request protocol**

The application must set the SRP-capable bit in the Core USB configuration register. This enables the OTG\_FS controller to detect SRP as an A-device.

**Figure 262. A-device SRP**

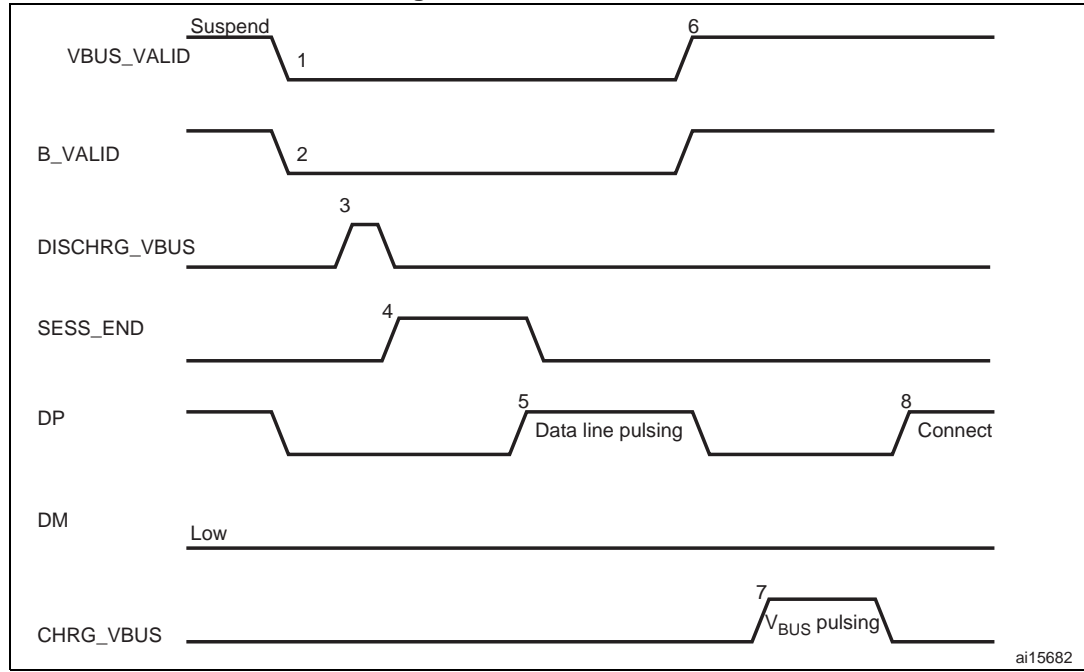


- 1. DRV\_VBUS =  $V_{BUS}$  drive signal to the PHY  
 VBUS\_VALID =  $V_{BUS}$  valid signal from PHY  
 A\_VALID = A-peripheral  $V_{BUS}$  level signal to PHY  
 D+ = Data plus line  
 D- = Data minus line
- 1. To save power, the application suspends and turns off port power when the bus is idle by writing the port suspend and port power bits in the host port control and status register.
- 2. PHY indicates port power off by deasserting the VBUS\_VALID signal.
- 3. The device must detect SE0 for at least 2 ms to start SRP when  $V_{BUS}$  power is off.
- 4. To initiate SRP, the device turns on its data line pull-up resistor for 5 to 10 ms. The OTG\_FS controller detects data-line pulsing.
- 5. The device drives  $V_{BUS}$  above the A-device session valid (2.0 V minimum) for  $V_{BUS}$  pulsing.  
 The OTG\_FS controller interrupts the application on detecting SRP. The Session request detected bit is set in Global interrupt status register (SRQINT set in OTG\_FS\_GINTSTS).
- 6. The application must service the Session request detected interrupt and turn on the port power bit by writing the port power bit in the host port control and status register. The PHY indicates port power-on by asserting the VBUS\_VALID signal.
- 7. When the USB is powered, the device connects, completing the SRP process.

### B-device session request protocol

The application must set the SRP-capable bit in the Core USB configuration register. This enables the OTG\_FS controller to initiate SRP as a B-device. SRP is a means by which the OTG\_FS controller can request a new session from the host.

Figure 263. B-device SRP



- 1. VBUS\_VALID = V<sub>BUS</sub> valid signal from PHY
- B\_VALID = B-peripheral valid session to PHY
- DISCHRG\_VBUS = discharge signal to PHY
- SESS\_END = session end signal to PHY
- CHRGR\_VBUS = charge V<sub>BUS</sub> signal to PHY
- DP = Data plus line
- DM = Data minus line

1. To save power, the host suspends and turns off port power when the bus is idle. The OTG\_FS controller sets the early suspend bit in the Core interrupt register after 3 ms of bus idleness. Following this, the OTG\_FS controller sets the USB suspend bit in the Core interrupt register. The OTG\_FS controller informs the PHY to discharge V<sub>BUS</sub>.
2. The PHY indicates the session's end to the device. This is the initial condition for SRP. The OTG\_FS controller requires 2 ms of SE0 before initiating SRP. For a USB 1.1 full-speed serial transceiver, the application must wait until V<sub>BUS</sub> discharges to 0.2 V after BSVLD (in OTG\_FS\_GOTGCTL) is deasserted. This discharge time can be obtained from the transceiver vendor and varies from one transceiver to another.
3. The USB OTG core informs the PHY to speed up V<sub>BUS</sub> discharge.
4. The application initiates SRP by writing the session request bit in the OTG Control and status register. The OTG\_FS controller perform data-line pulsing followed by V<sub>BUS</sub> pulsing.
5. The host detects SRP from either the data-line or V<sub>BUS</sub> pulsing, and turns on V<sub>BUS</sub>. The PHY indicates V<sub>BUS</sub> power-on to the device.

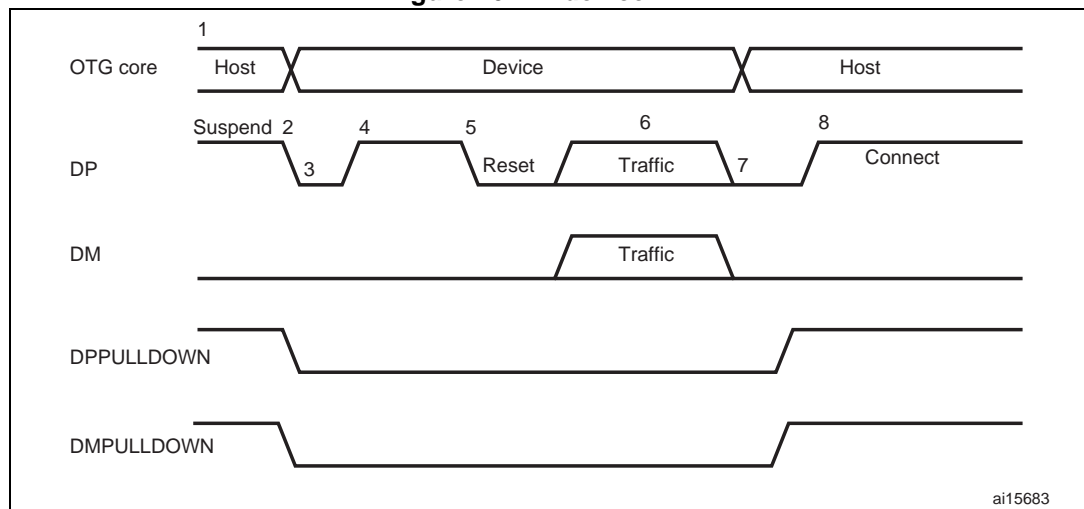


6. The OTG\_FS controller performs  $V_{BUS}$  pulsing.  
The host starts a new session by turning on  $V_{BUS}$ , indicating SRP success. The OTG\_FS controller interrupts the application by setting the session request success status change bit in the OTG interrupt status register. The application reads the session request success bit in the OTG control and status register.
7. When the USB is powered, the OTG\_FS controller connects, completing the SRP process.

**A-device host negotiation protocol**

HNP switches the USB host role from the A-device to the B-device. The application must set the HNP-capable bit in the Core USB configuration register to enable the OTG\_FS controller to perform HNP as an A-device.

**Figure 264. A-device HNP**



1. DPPULLDOWN = signal from core to PHY to enable/disable the pull-down on the DP line inside the PHY.  
DMPULLDOWN = signal from core to PHY to enable/disable the pull-down on the DM line inside the PHY.
1. The OTG\_FS controller sends the B-device a SetFeature b\_hnp\_enable descriptor to enable HNP support. The B-device's ACK response indicates that the B-device supports HNP. The application must set host Set HNP Enable bit in the OTG Control

and status register to indicate to the OTG\_FS controller that the B-device supports HNP.

2. When it has finished using the bus, the application suspends by writing the Port suspend bit in the host port control and status register.
3. When the B-device observes a USB suspend, it disconnects, indicating the initial condition for HNP. The B-device initiates HNP only when it must switch to the host role; otherwise, the bus continues to be suspended.

The OTG\_FS controller sets the host negotiation detected interrupt in the OTG interrupt status register, indicating the start of HNP.

The OTG\_FS controller deasserts the DM pull down and DM pull down in the PHY to indicate a device role. The PHY enables the OTG\_FS\_DP pull-up resistor to indicate a connect for B-device.

The application must read the current mode bit in the OTG Control and status register to determine device mode operation.

4. The B-device detects the connection, issues a USB reset, and enumerates the OTG\_FS controller for data traffic.
5. The B-device continues the host role, initiating traffic, and suspends the bus when done.

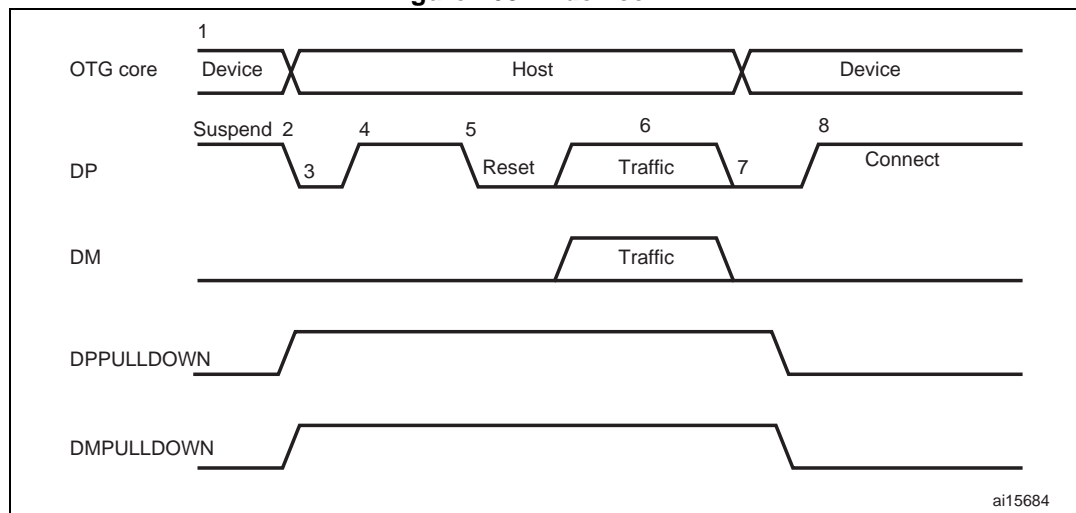
The OTG\_FS controller sets the early suspend bit in the Core interrupt register after 3 ms of bus idleness. Following this, the OTG\_FS controller sets the USB Suspend bit in the Core interrupt register.

6. In Negotiated mode, the OTG\_FS controller detects the suspend, disconnects, and switches back to the host role. The OTG\_FS controller asserts the DM pull down and DM pull down in the PHY to indicate its assumption of the host role.
7. The OTG\_FS controller sets the Connector ID status change interrupt in the OTG Interrupt Status register. The application must read the connector ID status in the OTG Control and Status register to determine the OTG\_FS controller operation as an A-device. This indicates the completion of HNP to the application. The application must read the Current mode bit in the OTG control and status register to determine host mode operation.
8. The B-device connects, completing the HNP process.

### B-device host negotiation protocol

HNP switches the USB host role from B-device to A-device. The application must set the HNP-capable bit in the Core USB configuration register to enable the OTG\_FS controller to perform HNP as a B-device.

Figure 265. B-device HNP



1. DPPULLDOWN = signal from core to PHY to enable/disable the pull-down on the DP line inside the PHY.  
DMPULLDOWN = signal from core to PHY to enable/disable the pull-down on the DM line inside the PHY.
1. The A-device sends the SetFeature b\_hnp\_enable descriptor to enable HNP support. The OTG\_FS controller's ACK response indicates that it supports HNP. The application must set the device HNP enable bit in the OTG Control and status register to indicate HNP support.  
The application sets the HNP request bit in the OTG Control and status register to indicate to the OTG\_FS controller to initiate HNP.
2. When it has finished using the bus, the A-device suspends by writing the Port suspend bit in the host port control and status register.  
The OTG\_FS controller sets the Early suspend bit in the Core interrupt register after 3 ms of bus idleness. Following this, the OTG\_FS controller sets the USB suspend bit in the Core interrupt register.  
The OTG\_FS controller disconnects and the A-device detects SE0 on the bus, indicating HNP. The OTG\_FS controller asserts the DP pull down and DM pull down in the PHY to indicate its assumption of the host role.  
The A-device responds by activating its OTG\_FS\_DP pull-up resistor within 3 ms of detecting SE0. The OTG\_FS controller detects this as a connect.  
The OTG\_FS controller sets the host negotiation success status change interrupt in the OTG Interrupt status register, indicating the HNP status. The application must read the host negotiation success bit in the OTG Control and status register to determine host negotiation success. The application must read the current Mode bit in the Core interrupt register (OTG\_FS\_GINTSTS) to determine host mode operation.
3. The application sets the reset bit (PRST in OTG\_FS\_HPRT) and the OTG\_FS controller issues a USB reset and enumerates the A-device for data traffic.
4. The OTG\_FS controller continues the host role of initiating traffic, and when done, suspends the bus by writing the Port suspend bit in the host port control and status register.

5. In Negotiated mode, when the A-device detects a suspend, it disconnects and switches back to the host role. The OTG\_FS controller deasserts the DP pull down and DM pull down in the PHY to indicate the assumption of the device role.
6. The application must read the current mode bit in the Core interrupt (OTG\_FS\_GINTSTS) register to determine the host mode operation.
7. The OTG\_FS controller connects, completing the HNP process.

## 23 Debug support (DBG)

### 23.1 Overview

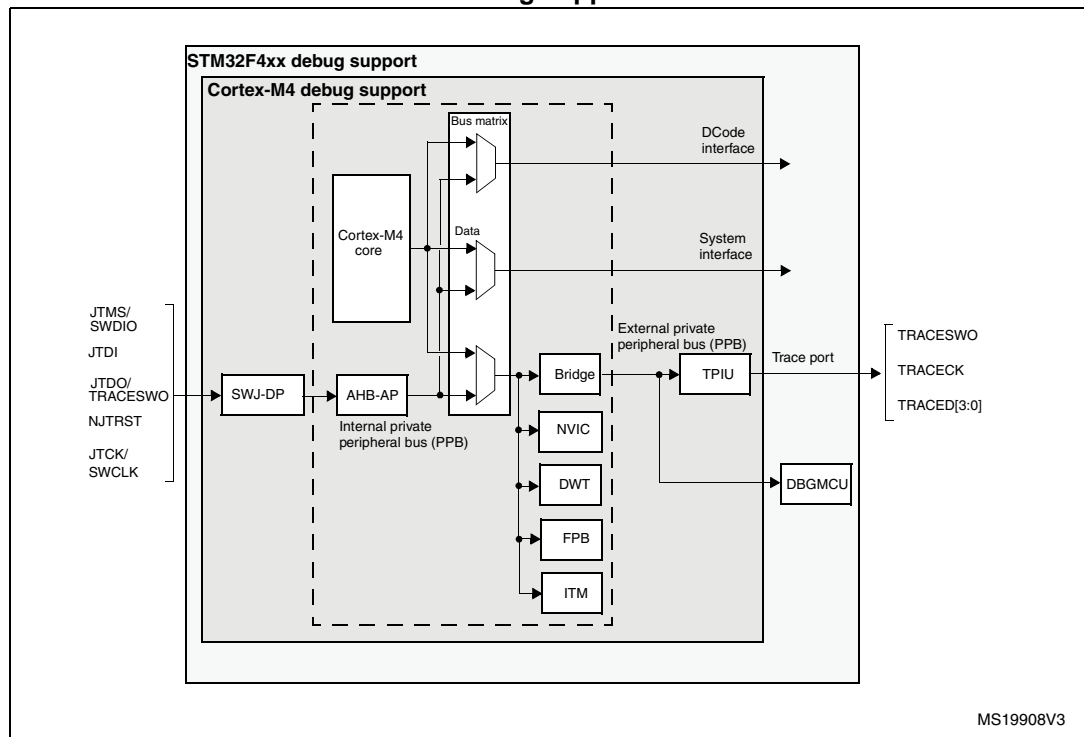
The STM32F401xB/C and STM32F401xD/E are built around a Cortex®-M4 with FPU core which contains hardware extensions for advanced debugging features. The debug extensions allow the core to be stopped either on a given instruction fetch (breakpoint) or data access (watchpoint). When stopped, the core's internal state and the system's external state may be examined. Once examination is complete, the core and the system may be restored and program execution resumed.

The debug features are used by the debugger host when connecting to and debugging the STM32F401xB/C and STM32F401xD/E MCUs.

Two interfaces for debug are available:

- Serial wire
- JTAG debug port

**Figure 266. Block diagram of STM32 MCU and Cortex®-M4 with FPU-level debug support**



*Note:* The debug features embedded in the Cortex®-M4 with FPU core are a subset of the ARM® CoreSight Design Kit.

The ARM® Cortex®-M4 with FPU core provides integrated on-chip debug support. It is comprised of:

- SWJ-DP: Serial wire / JTAG debug port
- AHP-AP: AHB access port
- ITM: Instrumentation trace macrocell
- FPB: Flash patch breakpoint
- DWT: Data watchpoint trigger
- TPUI: Trace port unit interface (available on larger packages, where the corresponding pins are mapped)
- ETM: Embedded Trace Macrocell (available on larger packages, where the corresponding pins are mapped)

It also includes debug features dedicated to the STM32F401xB/C and STM32F401xD/E:

- Flexible debug pinout assignment
- MCU debug box (support for low-power modes, control over peripheral clocks, etc.)

*Note:* For further information on debug functionality supported by the ARM® Cortex®-M4 with FPU core, refer to the Cortex®-M4 with FPU-r0p1 Technical Reference Manual and to the CoreSight Design Kit-r0p1 TRM (see [Section 23.2: Reference ARM® documentation](#)).

## 23.2 Reference ARM® documentation

- Cortex®-M4 with FPU r0p1 Technical Reference Manual (TRM)  
(see Related documents on page 1)
- ARM® Debug Interface V5
- ARM® CoreSight Design Kit revision r0p1 Technical Reference Manual

## 23.3 SWJ debug port (serial wire and JTAG)

The core of the STM32F401xB/C and STM32F401xD/E integrates the Serial Wire / JTAG Debug Port (SWJ-DP). It is an ARM® standard CoreSight debug port that combines a JTAG-DP (5-pin) interface and a SW-DP (2-pin) interface.

- The JTAG Debug Port (JTAG-DP) provides a 5-pin standard JTAG interface to the AHP-AP port.
- The Serial Wire Debug Port (SW-DP) provides a 2-pin (clock + data) interface to the AHP-AP port.

In the SWJ-DP, the two JTAG pins of the SW-DP are multiplexed with some of the five JTAG pins of the JTAG-DP.

Figure 267. SWJ debug port

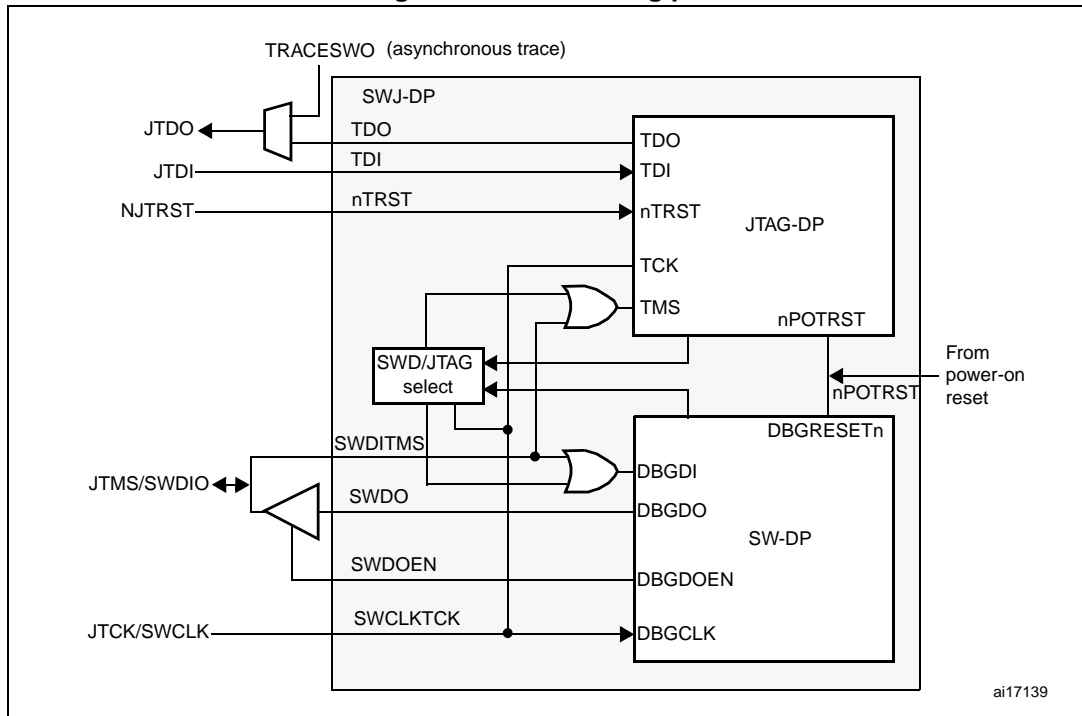


Figure 267 shows that the asynchronous TRACE output (TRACESWO) is multiplexed with TDO. This means that the asynchronous trace can only be used with SW-DP, not JTAG-DP.

### 23.3.1 Mechanism to select the JTAG-DP or the SW-DP

By default, the JTAG-Debug Port is active.

If the debugger host wants to switch to the SW-DP, it must provide a dedicated JTAG sequence on TMS/TCK (respectively mapped to SWDIO and SWCLK) which disables the JTAG-DP and enables the SW-DP. This way it is possible to activate the SWDP using only the SWCLK and SWDIO pins.

This sequence is:

1. Send more than 50 TCK cycles with TMS (SWDIO) =1
2. Send the 16-bit sequence on TMS (SWDIO) = 0111100111100111 (MSB transmitted first)
3. Send more than 50 TCK cycles with TMS (SWDIO) =1

### 23.4 Pinout and debug port pins

The STM32F401xB/C and STM32F401xD/E MCUs are available in various packages with different numbers of available pins. As a result, some functionality (ETM) related to pin availability may differ between packages.

### 23.4.1 SWJ debug port pins

Five pins are used as outputs from the STM32F401xB/C and STM32F401xD/E for the SWJ-DP as *alternate functions* of general-purpose I/Os. These pins are available on all packages.

Table 134. SWJ debug port pins

SWJ-DP pin name	JTAG debug port		SW debug port		Pin assignment
	Type	Description	Type	Debug assignment	
JTMS/SWDIO	I	JTAG Test Mode Selection	IO	Serial Wire Data Input/Output	PA13
JTCK/SWCLK	I	JTAG Test Clock	I	Serial Wire Clock	PA14
JTDI	I	JTAG Test Data Input	-	-	PA15
JTDO/TRACESWO	O	JTAG Test Data Output	-	TRACESWO if async trace is enabled	PB3
NJTRST	I	JTAG Test nReset	-	-	PB4

### 23.4.2 Flexible SWJ-DP pin assignment

After RESET (SYSRESETn or PORESETn), all five pins used for the SWJ-DP are assigned as dedicated pins immediately usable by the debugger host (note that the trace outputs are not assigned except if explicitly programmed by the debugger host).

However, the STM32F401xB/C and STM32F401xD/E MCUs offers the possibility of disabling some or all of the SWJ-DP ports and so, of releasing the associated pins for general-purpose IO (GPIO) usage. For more details on how to disable SWJ-DP port pins, please refer to [Section 8.3.2: I/O pin multiplexer and mapping](#).

Table 135. Flexible SWJ-DP pin assignment

Available debug ports	SWJ IO pin assigned				
	PA13 / JTMS / SWDIO	PA14 / JTCK / SWCLK	PA15 / JTDI	PB3 / JTDO	PB4 / NJTRST
Full SWJ (JTAG-DP + SW-DP) - Reset State	X	X	X	X	X
Full SWJ (JTAG-DP + SW-DP) but without NJTRST	X	X	X	X	
JTAG-DP Disabled and SW-DP Enabled	X	X			
JTAG-DP Disabled and SW-DP Disabled	Released				

*Note:* When the APB bridge write buffer is full, it takes one extra APB cycle when writing the GPIO\_AFR register. This is because the deactivation of the JTAGSW pins is done in two cycles to guarantee a clean level on the nTRST and TCK input signals of the core.

- Cycle 1: the JTAGSW input signals to the core are tied to 1 or 0 (to 1 for nTRST, TDI and TMS, to 0 for TCK)
- Cycle 2: the GPIO controller takes the control signals of the SWJTAG IO pins (like controls of direction, pull-up/down, Schmitt trigger activation, etc.).



### 23.4.3 Internal pull-up and pull-down on JTAG pins

It is necessary to ensure that the JTAG input pins are not floating since they are directly connected to flip-flops to control the debug mode features. Special care must be taken with the SWCLK/TCK pin which is directly connected to the clock of some of these flip-flops.

To avoid any uncontrolled IO levels, the device embeds internal pull-ups and pull-downs on the JTAG input pins:

NJTRST: Internal pull-up  
JTDI: Internal pull-up  
JTMS/SWDIO: Internal pull-up  
TCK/SWCLK: Internal pull-down  
Once a JTAG IO is released by the user software, the GPIO controller takes control again. The reset states of the GPIO control registers put the I/Os in the equivalent state:

- NJTRST: AF input pull-up
- JTDI: AF input pull-up
- JTMS/SWDIO: AF input pull-up
- JTCK/SWCLK: AF input pull-down
- JTDO: AF output floating

The software can then use these I/Os as standard GPIOs.

*Note: The JTAG IEEE standard recommends to add pull-ups on TDI, TMS and nTRST but there is no special recommendation for TCK. However, for JTCK, the device needs an integrated pull-down.*

*Having embedded pull-ups and pull-downs removes the need to add external resistors.*

### 23.4.4 Using serial wire and releasing the unused debug pins as GPIOs

To use the serial wire DP to release some GPIOs, the user software must change the GPIO (PA15, PB3 and PB4) configuration mode in the GPIO\_MODER register. This releases PA15, PB3 and PB4 which now become available as GPIOs.

When debugging, the host performs the following actions:

- Under system reset, all SWJ pins are assigned (JTAG-DP + SW-DP).
- Under system reset, the debugger host sends the JTAG sequence to switch from the JTAG-DP to the SW-DP.
- Still under system reset, the debugger sets a breakpoint on vector reset.
- The system reset is released and the Core halts.
- All the debug communications from this point are done using the SW-DP. The other JTAG pins can then be reassigned as GPIOs by the user software.

*Note:* For user software designs, note that:

*To release the debug pins, remember that they will be first configured either in input-pull-up ( $nTRST$ ,  $TMS$ ,  $TDI$ ) or pull-down ( $TCK$ ) or output tristate ( $TDO$ ) for a certain duration after reset until the instant when the user software releases the pins.*

*When debug pins (JTAG or SW or TRACE) are mapped, changing the corresponding IO pin configuration in the IOPORT controller has no effect.*

## 23.5 STM32F401xB/C and STM32F401xD/E JTAG TAP connection

The STM32F401xB/C and STM32F401xD/E MCUs integrate two serially connected JTAG TAPs, the boundary scan TAP (IR is 5-bit wide) and the Cortex<sup>®</sup>-M4 with FPU TAP (IR is 4-bit wide).

To access the TAP of the Cortex<sup>®</sup>-M4 with FPU for debug purposes:

1. First, it is necessary to shift the BYPASS instruction of the boundary scan TAP.
2. Then, for each IR shift, the scan chain contains 9 bits (=5+4) and the unused TAP instruction must be shifted in using the BYPASS instruction.
3. For each data shift, the unused TAP, which is in BYPASS mode, adds 1 extra data bit in the data scan chain.

*Note:* **Important:** Once Serial-Wire is selected using the dedicated ARM<sup>®</sup> JTAG sequence, the boundary scan TAP is automatically disabled (JTMS forced high).



## 23.6 ID codes and locking mechanism

There are several ID codes inside the STM32F401xB/C and STM32F401xD/E MCUs. ST strongly recommends tools designers to lock their debuggers using the MCU DEVICE ID code located in the external PPB memory map at address 0xE0042000.

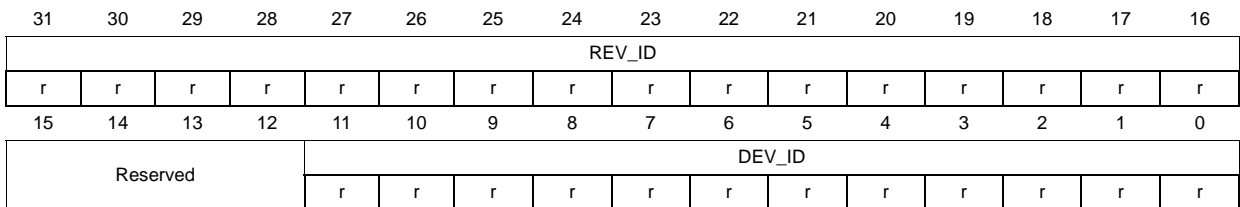
### 23.6.1 MCU device ID code

The STM32F401xB/C and STM32F401xD/E MCUs integrate an MCU ID code. This ID identifies the ST MCU part-number and the die revision. It is part of the DBG\_MCU component and is mapped on the external PPB bus (see [Section 23.16 on page 819](#)). This code is accessible using the JTAG debug port (4 to 5 pins) or the SW debug port (two pins) or by the user software. It is even accessible while the MCU is under system reset.

#### DBGMCU\_IDCODE

Address: 0xE004 2000

Only 32-bits access supported. Read-only.



Bits 31:16 **REV\_ID(15:0)** Revision identifier

This field indicates the revision of the device:

STM32F401xB/C devices

0x1000 = Revision Z

0x1001 = Revision A

STM32F401xD/E devices

0x1000 = Revision A

0x1001 = Revision Z

Bits 15:12 Reserved, must be kept at reset value.

Bits 11:0 **DEV\_ID(11:0)**: Device identifier

The device ID is 0x423 for STM32F401xB/C.

The device ID is 0x433 for STM32F401xD/E.

### 23.6.2 Boundary scan TAP

#### JTAG ID code

The TAP of the STM32F401xB/C and STM32F401xD/E BSC (boundary scan) integrates a JTAG ID code equal to:

- 0x06423041 for STM32F401xB/C
- 0x06433041 for STM32F401xD/E

### 23.6.3 Cortex<sup>®</sup>-M4 with FPU TAP

The TAP of the ARM<sup>®</sup> Cortex<sup>®</sup>-M4 with FPU integrates a JTAG ID code. This ID code is the ARM<sup>®</sup> default one and has not been modified. This code is only accessible by the JTAG Debug Port.

This code is (corresponds to Cortex<sup>®</sup>-M4 with FPU r0p1, see [Section 23.2: Reference ARM<sup>®</sup> documentation](#)).

Only the DEV\_ID(11:0) should be used for identification by the debugger/programmer tools.

### 23.6.4 Cortex<sup>®</sup>-M4 with FPU JEDEC-106 ID code

The ARM<sup>®</sup> Cortex<sup>®</sup>-M4 with FPU integrates a JEDEC-106 ID code. It is located in the 4KB ROM table mapped on the internal PPB bus at address 0xE00FF000\_0xE00FFFFF.

This code is accessible by the JTAG Debug Port (4 to 5 pins) or by the SW Debug Port (two pins) or by the user software.

## 23.7 JTAG debug port

A standard JTAG state machine is implemented with a 4-bit instruction register (IR) and five data registers (for full details, refer to the Cortex<sup>®</sup>-M4 with FPU r0p1 *Technical Reference Manual (TRM)*, for references, please see [Section 23.2: Reference ARM<sup>®</sup> documentation](#)).

**Table 136. JTAG debug port data registers**

IR(3:0)	Data register	Details
1111	BYPASS [1 bit]	
1110	IDCODE [32 bits]	ID CODE 0x4BA00477 (ARM <sup>®</sup> Cortex <sup>®</sup> -M4 with FPU r0p1 ID Code)
1010	DPACC [35 bits]	Debug port access register This initiates a debug port and allows access to a debug port register. – When transferring data IN: Bits 34:3 = DATA[31:0] = 32-bit data to transfer for a write request Bits 2:1 = A[3:2] = 2-bit address of a debug port register. Bit 0 = RnW = Read request (1) or write request (0). – When transferring data OUT: Bits 34:3 = DATA[31:0] = 32-bit data which is read following a read request Bits 2:0 = ACK[2:0] = 3-bit Acknowledge: 010 = OK/FAULT 001 = WAIT OTHER = reserved Refer to <a href="#">Table 137</a> for a description of the A[3:2] bits

**Table 136. JTAG debug port data registers (continued)**

IR(3:0)	Data register	Details
1011	APACC [35 bits]	<p>Access port access register Initiates an access port and allows access to an access port register.</p> <ul style="list-style-type: none"> <li>- When transferring data IN:                             <ul style="list-style-type: none"> <li>Bits 34:3 = DATA[31:0] = 32-bit data to shift in for a write request</li> <li>Bits 2:1 = A[3:2] = 2-bit address (sub-address AP registers).</li> <li>Bit 0 = RnW= Read request (1) or write request (0).</li> </ul> </li> <li>- When transferring data OUT:                             <ul style="list-style-type: none"> <li>Bits 34:3 = DATA[31:0] = 32-bit data which is read following a read request</li> <li>Bits 2:0 = ACK[2:0] = 3-bit Acknowledge:                                     <ul style="list-style-type: none"> <li>010 = OK/FAULT</li> <li>001 = WAIT</li> <li>OTHER = reserved</li> </ul> </li> </ul> </li> </ul> <p>There are many AP Registers (see AHB-AP) addressed as the combination of:</p> <ul style="list-style-type: none"> <li>- The shifted value A[3:2]</li> <li>- The current value of the DP SELECT register</li> </ul>
1000	ABORT [35 bits]	<p>Abort register</p> <ul style="list-style-type: none"> <li>- Bits 31:1 = Reserved</li> <li>- Bit 0 = DAPABORT: write 1 to generate a DAP abort.</li> </ul>

**Table 137. 32-bit debug port registers addressed through the shifted value A[3:2]**

Address	A[3:2] value	Description
0x0	00	Reserved, must be kept at reset value.
0x4	01	<p>DP CTRL/STAT register. Used to:</p> <ul style="list-style-type: none"> <li>- Request a system or debug power-up</li> <li>- Configure the transfer operation for AP accesses</li> <li>- Control the pushed compare and pushed verify operations.</li> <li>- Read some status flags (overrun, power-up acknowledges)</li> </ul>
0x8	10	<p>DP SELECT register: Used to select the current access port and the active 4-words register window.</p> <ul style="list-style-type: none"> <li>- Bits 31:24: APSEL: select the current AP</li> <li>- Bits 23:8: reserved</li> <li>- Bits 7:4: APBANKSEL: select the active 4-words register window on the current AP</li> <li>- Bits 3:0: reserved</li> </ul>
0xC	11	<p>DP RDBUFF register: Used to allow the debugger to get the final result after a sequence of operations (without requesting new JTAG-DP operation)</p>

## 23.8 SW debug port

### 23.8.1 SW protocol introduction

This synchronous serial protocol uses two pins:

- SWCLK: clock from host to target
- SWDIO: bidirectional

The protocol allows two banks of registers (DPACC registers and APACC registers) to be read and written to.

Bits are transferred LSB-first on the wire.

For SWDIO bidirectional management, the line must be pulled-up on the board (100 KΩ recommended by ARM®).

Each time the direction of SWDIO changes in the protocol, a turnaround time is inserted where the line is not driven by the host nor the target. By default, this turnaround time is one bit time, however this can be adjusted by configuring the SWCLK frequency.

### 23.8.2 SW protocol sequence

Each sequence consist of three phases:

1. Packet request (8 bits) transmitted by the host
2. Acknowledge response (3 bits) transmitted by the target
3. Data transfer phase (33 bits) transmitted by the host or the target

**Table 138. Packet request (8-bits)**

Bit	Name	Description
0	Start	Must be "1"
1	APnDP	0: DP Access 1: AP Access
2	RnW	0: Write Request 1: Read Request
4:3	A[3:2]	Address field of the DP or AP registers (refer to <a href="#">Table 137</a> )
5	Parity	Single bit parity of preceding bits
6	Stop	0
7	Park	Not driven by the host. Must be read as "1" by the target because of the pull-up

Refer to the Cortex®-M4 with FPUr0p1 *TRM* for a detailed description of DPACC and APACC registers.

The packet request is always followed by the turnaround time (default 1 bit) where neither the host nor target drive the line.

**Table 139. ACK response (3 bits)**

Bit	Name	Description
0..2	ACK	001: FAULT 010: WAIT 100: OK

The ACK Response must be followed by a turnaround time only if it is a READ transaction or if a WAIT or FAULT acknowledge has been received.

**Table 140. DATA transfer (33 bits)**

Bit	Name	Description
0..31	WDATA or RDATA	Write or Read data
32	Parity	Single parity of the 32 data bits

The DATA transfer must be followed by a turnaround time only if it is a READ transaction.

### 23.8.3 SW-DP state machine (reset, idle states, ID code)

The State Machine of the SW-DP has an internal ID code which identifies the SW-DP. It follows the JEP-106 standard. This ID code is the default ARM<sup>®</sup> one and is set to **0x2BA01477** (corresponding to Cortex<sup>®</sup>-M4 with FPU r0p1).

*Note:* Note that the SW-DP state machine is inactive until the target reads this ID code.

- The SW-DP state machine is in RESET STATE either after power-on reset, or after the DP has switched from JTAG to SWD or after the line is high for more than 50 cycles
- The SW-DP state machine is in IDLE STATE if the line is low for at least two cycles after RESET state.
- After RESET state, it is **mandatory** to first enter into an IDLE state AND to perform a READ access of the DP-SW ID CODE register. Otherwise, the target will issue a FAULT acknowledge response on another transactions.

Further details of the SW-DP state machine can be found in the Cortex<sup>®</sup>-M4 with FPU r0p1 TRM and the CoreSight Design Kit r0p1 TRM.

### 23.8.4 DP and AP read/write accesses

- Read accesses to the DP are not posted: the target response can be immediate (if ACK=OK) or can be delayed (if ACK=WAIT).
- Read accesses to the AP are posted. This means that the result of the access is returned on the next transfer. If the next access to be done is NOT an AP access, then the DP-RDBUFF register must be read to obtain the result. The READOK flag of the DP-CTRL/STAT register is updated on every AP read access or RDBUFF read request to know if the AP read access was successful.
- The SW-DP implements a write buffer (for both DP or AP writes), that enables it to accept a write operation even when other transactions are still outstanding. If the write buffer is full, the target acknowledge response is "WAIT". With the exception of



IDCODE read or CTRL/STAT read or ABORT write which are accepted even if the write buffer is full.

- Because of the asynchronous clock domains SWCLK and HCLK, two extra SWCLK cycles are needed after a write transaction (after the parity bit) to make the write effective internally. These cycles should be applied while driving the line low (IDLE state)  
This is particularly important when writing the CTRL/STAT for a power-up request. If the next transaction (requiring a power-up) occurs immediately, it will fail.

### 23.8.5 SW-DP registers

Access to these registers are initiated when APnDP=0

Table 141. SW-DP registers

A[3:2]	R/W	CTRLSEL bit of SELECT register	Register	Notes
00	Read	-	IDCODE	The manufacturer code is not set to ST code. <b>0x2BA01477</b> (identifies the SW-DP)
00	Write	-	ABORT	-
01	Read/Write	0	DP-CTRL/STAT	Purpose is to: <ul style="list-style-type: none"> <li>– request a system or debug power-up</li> <li>– configure the transfer operation for AP accesses</li> <li>– control the pushed compare and pushed verify operations.</li> <li>– read some status flags (overrun, power-up acknowledges)</li> </ul>
01	Read/Write	1	WIRE CONTROL	Purpose is to configure the physical serial port protocol (like the duration of the turnaround time)
10	Read		READ RESEND	Enables recovery of the read data from a corrupted debugger transfer, without repeating the original AP transfer.
10	Write		SELECT	The purpose is to select the current access port and the active 4-words register window
11	Read/Write		READ BUFFER	This read buffer is useful because AP accesses are posted (the result of a read AP request is available on the next AP transaction). This read buffer captures data from the AP, presented as the result of a previous read, without initiating a new transaction

### 23.8.6 SW-AP registers

Access to these registers are initiated when APnDP=1

There are many AP Registers (see AHB-AP) addressed as the combination of:

- The shifted value A[3:2]
- The current value of the DP SELECT register

## 23.9 AHB-AP (AHB access port) - valid for both JTAG-DP and SW-DP

### Features:

- System access is independent of the processor status.
- Either SW-DP or JTAG-DP accesses AHB-AP.
- The AHB-AP is an AHB master into the Bus Matrix. Consequently, it can access all the data buses (Dcode Bus, System Bus, internal and external PPB bus) but the ICode bus.
- Bitband transactions are supported.
- AHB-AP transactions bypass the FPB.

The address of the 32-bits AHP-AP registers are 6-bits wide (up to 64 words or 256 bytes) and consists of:

- Bits [7:4] = the bits [7:4] APBANKSEL of the DP SELECT register
- Bits [3:2] = the 2 address bits of A[3:2] of the 35-bit packet request for SW-DP.

The AHB-AP of the Cortex<sup>®</sup>-M4 with FPU includes 9 x 32-bits registers:

**Table 142. Cortex<sup>®</sup>-M4 with FPU AHB-AP registers**

Address offset	Register name	Notes
0x00	AHB-AP Control and Status Word	Configures and controls transfers through the AHB interface (size, hprot, status on current transfer, address increment type)
0x04	AHB-AP Transfer Address	-
0x0C	AHB-AP Data Read/Write	-
0x10	AHB-AP Banked Data 0	Directly maps the 4 aligned data words without rewriting the Transfer Address Register.
0x14	AHB-AP Banked Data 1	
0x18	AHB-AP Banked Data 2	
0x1C	AHB-AP Banked Data 3	
0xF8	AHB-AP Debug ROM Address	Base Address of the debug interface
0xFC	AHB-AP ID Register	-

Refer to the Cortex<sup>®</sup>-M4 with FPU *r0p1 TRM* for further details.

## 23.10 Core debug

Core debug is accessed through the core debug registers. Debug access to these registers is by means of the *Advanced High-performance Bus* (AHB-AP) port. The processor can access these registers directly over the internal *Private Peripheral Bus* (PPB).

It consists of 4 registers:

**Table 143. Core debug registers**

Register	Description
DHCSR	The 32-bit Debug Halting Control and Status Register This provides status information about the state of the processor enable core debug halt and step the processor
DCRSR	The 17-bit Debug Core Register Selector Register: This selects the processor register to transfer data to or from.
DCRDR	The 32-bit Debug Core Register Data Register: This holds data for reading and writing registers to and from the processor selected by the DCRSR (Selector) register.
DEMCR	The 32-bit Debug Exception and Monitor Control Register: This provides Vector Catching and Debug Monitor Control. This register contains a bit named <b>TRCENA</b> which enable the use of a TRACE.

*Note:* **Important:** these registers are not reset by a system reset. They are only reset by a power-on reset.

Refer to the *Cortex®-M4 with FPU r0p1 TRM* for further details.

To Halt on reset, it is necessary to:

- enable the bit0 (VC\_CORRESET) of the Debug and Exception Monitor Control Register
- enable the bit0 (C\_DEBUGEN) of the Debug Halting Control and Status Register.

## 23.11 Capability of the debugger host to connect under system reset

The reset system of the STM32F401xB/C and STM32F401xD/E MCU comprises the following reset sources:

- POR (power-on reset) which asserts a RESET at each power-up.
- Internal watchdog reset
- Software reset
- External reset

The Cortex<sup>®</sup>-M4 with FPU differentiates the reset of the debug part (generally PORRESETn) and the other one (SYSRESETn)

This way, it is possible for the debugger to connect under System Reset, programming the Core Debug Registers to halt the core when fetching the reset vector. Then the host can release the system reset and the core will immediately halt without having executed any instructions. In addition, it is possible to program any debug features under System Reset.

*Note: It is highly recommended for the debugger host to connect (set a breakpoint in the reset vector) under system reset.*

## 23.12 FPB (Flash patch breakpoint)

The FPB unit:

- implements hardware breakpoints
- patches code and data from code space to system space. This feature gives the possibility to correct software bugs located in the Code Memory Space.

The use of a Software Patch or a Hardware Breakpoint is exclusive.

The FPB consists of:

- 2 literal comparators for matching against literal loads from Code Space and remapping to a corresponding area in the System Space.
- 6 instruction comparators for matching against instruction fetches from Code Space. They can be used either to remap to a corresponding area in the System Space or to generate a Breakpoint Instruction to the core.

## 23.13 DWT (data watchpoint trigger)

The DWT unit consists of four comparators. They are configurable as:

- a hardware watchpoint or
- a trigger to an ETM or
- a PC sampler or
- a data address sampler

The DWT also provides some means to give some profiling informations. For this, some counters are accessible to give the number of:

- Clock cycle
- Folded instructions
- Load store unit (LSU) operations
- Sleep cycles
- CPI (clock per instructions)
- Interrupt overhead

## 23.14 ITM (instrumentation trace macrocell)

### 23.14.1 General description

The ITM is an application-driven trace source that supports *printf* style debugging to trace *Operating System* (OS) and application events, and emits diagnostic system information. The ITM emits trace information as packets which can be generated as:

- **Software trace.** Software can write directly to the ITM stimulus registers to emit packets.
- **Hardware trace.** The DWT generates these packets, and the ITM emits them.
- **Time stamping.** Timestamps are emitted relative to packets. The ITM contains a 21-bit counter to generate the timestamp. The Cortex<sup>®</sup>-M4 with FPU clock or the bit clock rate of the *Serial Wire Viewer* (SWV) output clocks the counter.

The packets emitted by the ITM are output to the TPIU (Trace Port Interface Unit). The formatter of the TPIU adds some extra packets (refer to TPIU) and then output the complete packets sequence to the debugger host.

The bit TRCEN of the Debug Exception and Monitor Control Register must be enabled before you program or use the ITM.

### 23.14.2 Time stamp packets, synchronization and overflow packets

Time stamp packets encode time stamp information, generic control and synchronization. It uses a 21-bit timestamp counter (with possible prescalers) which is reset at each time stamp packet emission. This counter can be either clocked by the CPU clock or the SWV clock.

A synchronization packet consists of 6 bytes equal to 0x80\_00\_00\_00\_00\_00 which is emitted to the TPIU as 00 00 00 00 00 80 (LSB emitted first).

A synchronization packet is a timestamp packet control. It is emitted at each DWT trigger.

For this, the DWT must be configured to trigger the ITM: the bit CYCCNTENA (bit0) of the DWT Control Register must be set. In addition, the bit2 (SYNCENA) of the ITM Trace Control Register must be set.

*Note: If the SYNENA bit is not set, the DWT generates Synchronization triggers to the TPIU which will send only TPIU synchronization packets and not ITM synchronization packets.*

An overflow packet consists is a special timestamp packets which indicates that data has been written but the FIFO was full.

**Table 144. Main ITM registers**

Address	Register	Details
@E0000FB0	ITM lock access	Write 0xC5ACCE55 to unlock Write Access to the other ITM registers
@E0000E80	ITM trace control	Bits 31-24 = Always 0
		Bits 23 = Busy
		Bits 22-16 = 7-bits ATB ID which identifies the source of the trace data.
		Bits 15-10 = Always 0
		Bits 9:8 = TSPrescale = Time Stamp Prescaler
		Bits 7-5 = Reserved
		Bit 4 = SWOENA = Enable SWV behavior (to clock the timestamp counter by the SWV clock).
		Bit 3 = DWTENA: Enable the DWT Stimulus
		Bit 2 = SYNCENA: this bit must be to 1 to enable the DWT to generate synchronization triggers so that the TPIU can then emit the synchronization packets.
		Bit 1 = TSENA (Timestamp Enable)
Bit 0 = ITMENA: Global Enable Bit of the ITM		
@E0000E40	ITM trace privilege	Bit 3: mask to enable tracing ports31:24
		Bit 2: mask to enable tracing ports23:16
		Bit 1: mask to enable tracing ports15:8
		Bit 0: mask to enable tracing ports7:0
@E0000E00	ITM trace enable	Each bit enables the corresponding Stimulus port to generate trace.
@E0000000- E000007C	Stimulus port registers 0-31	Write the 32-bits data on the selected Stimulus Port (32 available) to be traced out.

**Example of configuration**

To output a simple value to the TPIU:

- Configure the TPIU and assign TRACE I/Os by configuring the DBGMCU\_CR (refer to [Section 23.17.2: TRACE pin assignment](#) and [Section 23.16.3: Debug MCU](#))



*configuration register*)

- Write 0xC5ACCE55 to the ITM Lock Access Register to unlock the write access to the ITM registers
- Write 0x00010005 to the ITM Trace Control Register to enable the ITM with Sync enabled and an ATB ID different from 0x00
- Write 0x1 to the ITM Trace Enable Register to enable the Stimulus Port 0
- Write 0x1 to the ITM Trace Privilege Register to unmask stimulus ports 7:0
- Write the value to output in the Stimulus Port Register 0: this can be done by software (using a printf function)

## 23.15 ETM (Embedded trace macrocell)

### 23.15.1 General description

The ETM enables the reconstruction of program execution. Data are traced using the Data Watchpoint and Trace (DWT) component or the Instruction Trace Macrocell (ITM) whereas instructions are traced using the Embedded Trace Macrocell (ETM).

The ETM transmits information as packets and is triggered by embedded resources. These resources must be programmed independently and the trigger source is selected using the Trigger Event Register (0xE0041008). An event could be a simple event (address match from an address comparator) or a logic equation between 2 events. The trigger source is one of the fourth comparators of the DWT module, The following events can be monitored:

- Clock cycle matching
- Data address matching

For more informations on the trigger resources refer to [Section 23.13: DWT \(data watchpoint trigger\)](#).

The packets transmitted by the ETM are output to the TPIU (Trace Port Interface Unit). The formatter of the TPIU adds some extra packets (refer to [Section 23.17: TPIU \(trace port interface unit\)](#)) and then outputs the complete packet sequence to the debugger host.

### 23.15.2 Signal protocol, packet types

This part is described in the chapter 7 ETMv3 Signal Protocol of the ARM® IHI 0014N document.

### 23.15.3 Main ETM registers

For more information on registers refer to the chapter 3 of the ARM® IHI 0014N specification.

**Table 145. Main ETM registers**

Address	Register	Details
0xE0041FB0	ETM Lock Access	Write 0xC5ACCE55 to unlock the write access to the other ETM registers.
0xE0041000	ETM Control	This register controls the general operation of the ETM, for instance how tracing is enabled.

**Table 145. Main ETM registers (continued)**

Address	Register	Details
0xE0041010	ETM Status	This register provides information about the current status of the trace and trigger logic.
0xE0041008	ETM Trigger Event	This register defines the event that will control trigger.
0xE004101C	ETM Trace Enable Control	This register defines which comparator is selected.
0xE0041020	ETM Trace Enable Event	This register defines the trace enabling event.
0xE0041024	ETM Trace Start/Stop	This register defines the traces used by the trigger source to start and stop the trace, respectively.

### 23.15.4 Configuration example

To output a simple value to the TPIU:

- Configure the TPIU and enable the I/O\_TRACEN to assign TRACE I/Os in the STM32F401xB/C and STM32F401xD/E debug configuration register.
- Write 0xC5ACCE55 to the ETM Lock Access Register to unlock the write access to the ITM registers
- Write 0x00001D1E to the control register (configure the trace)
- Write 0000406F to the Trigger Event register (define the trigger event)
- Write 0000006F to the Trace Enable Event register (define an event to start/stop)
- Write 00000001 to the Trace Start/stop register (enable the trace)
- Write 0000191E to the ETM Control Register (end of configuration)

## 23.16 MCU debug component (DBGMCU)

The MCU debug component helps the debugger provide support for:

- Low-power modes
- Clock control for timers, watchdog and I2C during a breakpoint
- Control of the trace pins assignment

### 23.16.1 Debug support for low-power modes

To enter low-power mode, the instruction WFI or WFE must be executed.

The MCU implements several low-power modes which can either deactivate the CPU clock or reduce the power of the CPU.

The core does not allow FCLK or HCLK to be turned off during a debug session. As these are required for the debugger connection, during a debug, they must remain active. The MCU integrates special means to allow the user to debug software in low-power modes.



For this, the debugger host must first set some debug configuration registers to change the low-power mode behavior:

- In Sleep mode, DBG\_SLEEP bit of DBGMCU\_CR register must be previously set by the debugger. This will feed HCLK with the same clock that is provided to FCLK (system clock previously configured by the software).
- In Stop mode, the bit DBG\_STOP must be previously set by the debugger. This will enable the internal RC oscillator clock to feed FCLK and HCLK in STOP mode.

### 23.16.2 Debug support for timers, watchdog and I<sup>2</sup>C

During a breakpoint, it is necessary to choose how the counter of timers and watchdog should behave:

- They can continue to count inside a breakpoint. This is usually required when a PWM is controlling a motor, for example.
- They can stop to count inside a breakpoint. This is required for watchdog purposes.

For the I<sup>2</sup>C, the user can choose to block the SMBUS timeout during a breakpoint.

### 23.16.3 Debug MCU configuration register

This register allows the configuration of the MCU under DEBUG. This concerns:

- Low-power mode support
- Timer and watchdog counter support
- Trace pin assignment

This DBGMCU\_CR is mapped on the External PPB bus at address 0xE0042004

It is asynchronously reset by the PORESET (and not the system reset). It can be written by the debugger under system reset.

If the debugger host does not support these features, it is still possible for the user software to write to these registers.

#### DBGMCU\_CR register

Address: 0xE004 2004

Only 32-bit access supported

POR Reset: 0x0000 0000 (not reset by system reset)

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16		
Reserved																	
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0		
Reserved								TRACE_MODE [1:0]		TRACE_IOEN		Reserved			DBG_STANDBY	DBG_STOP	DBG_SLEEP
								rw	rw	rw					rw	rw	rw

Bits 31:8 Reserved, must be kept at reset value.

Bits 7:5 **TRACE\_MODE[1:0] and TRACE\_IOEN**: Trace pin assignment control

- With TRACE\_IOEN=0:
  - TRACE\_MODE=xx: TRACE pins not assigned (default state)
- With TRACE\_IOEN=1:
  - TRACE\_MODE=00: TRACE pin assignment for Asynchronous Mode
  - TRACE\_MODE=01: TRACE pin assignment for Synchronous Mode with a TRACEDATA size of 1
  - TRACE\_MODE=10: TRACE pin assignment for Synchronous Mode with a TRACEDATA size of 2
  - TRACE\_MODE=11: TRACE pin assignment for Synchronous Mode with a TRACEDATA size of 4

Bits 4:3 Reserved, must be kept at reset value.

Bit 2 **DBG\_STANDBY**: Debug Standby mode

0: (FCLK=Off, HCLK=Off) The whole digital part is unpowered.

From software point of view, exiting from Standby is identical than fetching reset vector (except a few status bit indicated that the MCU is resuming from Standby)

1: (FCLK=On, HCLK=On) In this case, the digital part is not unpowered and FCLK and HCLK are provided by the internal RC oscillator which remains active. In addition, the MCU generate a system reset during Standby mode so that exiting from Standby is identical than fetching from reset

Bit 1 **DBG\_STOP**: Debug Stop mode

0: (FCLK=Off, HCLK=Off) In STOP mode, the clock controller disables all clocks (including HCLK and FCLK). When exiting from STOP mode, the clock configuration is identical to the one after RESET (CPU clocked by the 8 MHz internal RC oscillator (HSI)). Consequently, the software must reprogram the clock controller to enable the PLL, the Xtal, etc.

1: (FCLK=On, HCLK=On) In this case, when entering STOP mode, FCLK and HCLK are provided by the internal RC oscillator which remains active in STOP mode. When exiting STOP mode, the software must reprogram the clock controller to enable the PLL, the Xtal, etc. (in the same way it would do in case of DBG\_STOP=0)

Bit 0 **DBG\_SLEEP**: Debug Sleep mode

0: (FCLK=On, HCLK=Off) In Sleep mode, FCLK is clocked by the system clock as previously configured by the software while HCLK is disabled.

In Sleep mode, the clock controller configuration is not reset and remains in the previously programmed state. Consequently, when exiting from Sleep mode, the software does not need to reconfigure the clock controller.

1: (FCLK=On, HCLK=On) In this case, when entering Sleep mode, HCLK is fed by the same clock that is provided to FCLK (system clock as previously configured by the software).

#### 23.16.4 Debug MCU APB1 freeze register (DBGMCU\_APB1\_FZ)

The DBGMCU\_APB1\_FZ register is used to configure the MCU under Debug. It concerns APB1 peripherals. It is mapped on the external PPB bus at address 0xE004 2008.

The register is asynchronously reset by the POR (and not the system reset). It can be written by the debugger under system reset.

Address : 0xE004 2008

Only 32-bits access are supported.

Power-on reset (POR): 0x0000 0000 (not reset by system reset)

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved								DBG_I2C3_SMBUS_TIMEOUT	DBG_I2C2_SMBUS_TIMEOUT	DBG_I2C1_SMBUS_TIMEOUT	Reserved				
								rw	rw	rw					
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved			DBG_IWDG_STOP	DBG_WWDG_STOP	DBG_RTC_STOP	Reserved					DBG_TIM5_STOP	DBG_TIM4_STOP	DBG_TIM3_STOP	DBG_TIM2_STOP	

Bits 31:24 Reserved, must be kept at reset value.

Bit 23 **DBG\_I2C3\_SMBUS\_TIMEOUT**: SMBUS timeout mode stopped when Core is halted  
 0: Same behavior as in normal mode  
 1: The SMBUS timeout is frozen

Bit 22 **DBG\_I2C2\_SMBUS\_TIMEOUT**: SMBUS timeout mode stopped when Core is halted  
 0: Same behavior as in normal mode  
 1: The SMBUS timeout is frozen

Bit 21 **DBG\_I2C1\_SMBUS\_TIMEOUT**: SMBUS timeout mode stopped when Core is halted  
 0: Same behavior as in normal mode  
 1: The SMBUS timeout is frozen

Bit 20:13 Reserved, must be kept at reset value.

Bit 12 **DBG\_IWDG\_STOP**: Debug independent watchdog stopped when core is halted  
 0: The independent watchdog counter clock continues even if the core is halted  
 1: The independent watchdog counter clock is stopped when the core is halted

Bit 11 **DBG\_WWDG\_STOP**: Debug Window Watchdog stopped when Core is halted  
 0: The window watchdog counter clock continues even if the core is halted  
 1: The window watchdog counter clock is stopped when the core is halted

Bit 10 **DBG\_RTC\_STOP**: RTC stopped when Core is halted  
 0: The RTC counter clock continues even if the core is halted  
 1: The RTC counter clock is stopped when the core is halted

Bits 9:4 Reserved, must be kept at reset value.

Bits 3:0 **DBG\_TIMx\_STOP**: TIMx counter stopped when core is halted (x=2..5)  
 0: The clock of the involved Timer Counter is fed even if the core is halted  
 1: The clock of the involved Timer counter is stopped when the core is halted

### 23.16.5 Debug MCU APB2 Freeze register (DBGMCU\_APB2\_FZ)

The DBGMCU\_APB2\_FZ register is used to configure the MCU under Debug. It concerns APB2 peripherals.

This register is mapped on the external PPB bus at address 0xE004 200C

It is asynchronously reset by the POR (and not the system reset). It can be written by the debugger under system reset.

Address: 0xE004 200C

Only 32-bit access is supported.

POR: 0x0000 0000 (not reset by system reset)

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved													DBG_TIM11_STOP	DBG_TIM10_STOP	DBG_TIM9_STOP
													rw	rw	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved														DBG_TIM1_STOP	
														rw	

Bits 31:19 Reserved, must be kept at reset value.

Bits 18:16 **DBG\_TIMx\_STOP**: TIMx counter stopped when core is halted (x=9..11)

0: The clock of the involved Timer Counter is fed even if the core is halted

1: The clock of the involved Timer counter is stopped when the core is halted

Bits 15:1 Reserved, must be kept at reset value.

Bit 0 **DBG\_TIM1\_STOP**: TIM1 counter stopped when core is halted

0: The clock of the involved Timer Counter is fed even if the core is halted

1: The clock of the involved Timer counter is stopped when the core is halted

## 23.17 TPIU (trace port interface unit)

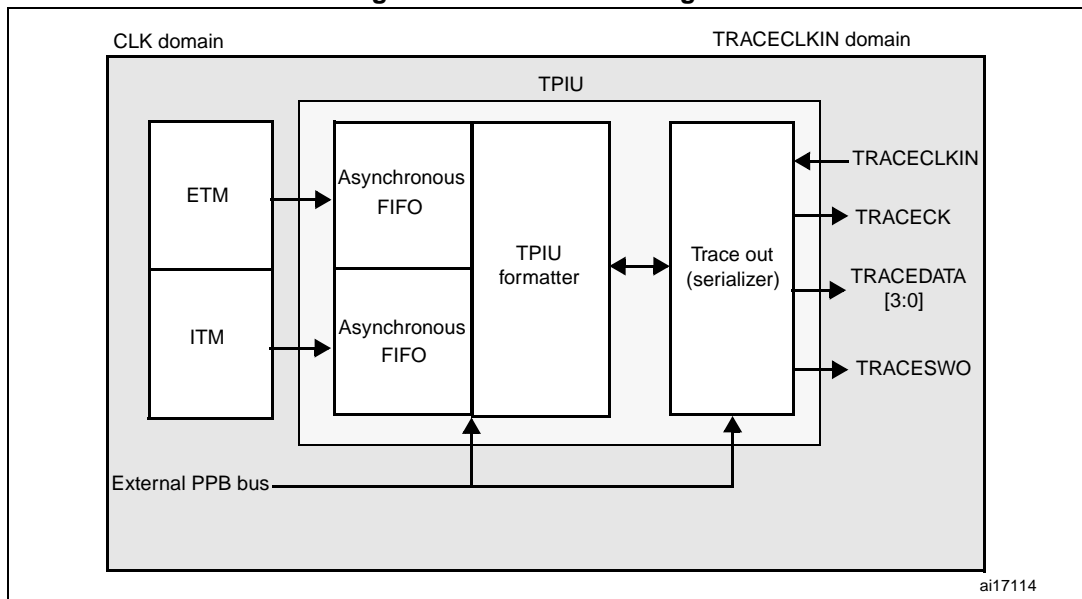
### 23.17.1 Introduction

The TPIU acts as a bridge between the on-chip trace data from the ITM and the ETM.

The output data stream encapsulates the trace source ID, that is then captured by a *trace port analyzer* (TPA).

The core embeds a simple TPIU, especially designed for low-cost debug (consisting of a special version of the CoreSight TPIU).

Figure 269. TPIU block diagram



### 23.17.2 TRACE pin assignment

- Asynchronous mode  
The asynchronous mode requires 1 extra pin and is available on all packages. It is only available if using Serial Wire mode (not in JTAG mode).

**Table 146. Asynchronous TRACE pin assignment**

TPUI pin name	Trace synchronous mode		pin assignment
	Type	Description	
TRACESWO	O	TRACE Async Data Output	PB3

- Synchronous mode  
The synchronous mode requires from 2 to 6 extra pins depending on the data trace size and is only available in the larger packages. In addition it is available in JTAG mode and in Serial Wire mode and provides better bandwidth output capabilities than asynchronous trace.

**Table 147. Synchronous TRACE pin assignment**

TPUI pin name	Trace synchronous mode		STM32F401xB/C and STM32F401xB/C pin assignment
	Type	Description	
TRACECK	O	TRACE Clock	PE2
TRACED[3:0]	O	TRACE Sync Data Outputs Can be 1, 2 or 4.	PE[6:3]

#### TPUI TRACE pin assignment

By default, these pins are NOT assigned. They can be assigned by setting the TRACE\_IOEN and TRACE\_MODE bits in the **MCU Debug component configuration register**. This configuration has to be done by the debugger host.

In addition, the number of pins to assign depends on the trace configuration (asynchronous or synchronous).

- Asynchronous mode:** 1 extra pin is needed
- Synchronous mode:** from 2 to 5 extra pins are needed depending on the size of the data trace port register (1, 2 or 4):
  - TRACECK
  - TRACED(0) if port size is configured to 1, 2 or 4
  - TRACED(1) if port size is configured to 2 or 4
  - TRACED(2) if port size is configured to 4
  - TRACED(3) if port size is configured to 4

To assign the TRACE pin, the debugger host must program the bits TRACE\_IOEN and TRACE\_MODE[1:0] of the Debug MCU configuration Register (DBGMCU\_CR). By default the TRACE pins are not assigned.

This register is mapped on the external PPB and is reset by the PORESET (and not by the SYSTEM reset). It can be written by the debugger under SYSTEM reset.

**Table 148. Flexible TRACE pin assignment**

DBGMCU_CR register		Pins assigned for:	TRACE IO pin assigned					
TRACE_IOEN	TRACE_MODE [1:0]		PB3 /JTDO/ TRACESWO	PE2/ TRACECK	PE3 / TRACED[0]	PE4 / TRACED[1]	PE5 / TRACED[2]	PE6 / TRACED[3]
0	XX	No Trace (default state)	Released <sup>(1)</sup>	-				
1	00	Asynchronous Trace	TRACESWO	-	-	Released (usable as GPIO)		
1	01	Synchronous Trace 1 bit	Released <sup>(1)</sup>	TRACECK	TRACED[0]	-	-	-
1	10	Synchronous Trace 2 bit		TRACECK	TRACED[0]	TRACED[1]	-	-
1	11	Synchronous Trace 4 bit		TRACECK	TRACED[0]	TRACED[1]	TRACED[2]	TRACED[3]

1. When Serial Wire mode is used, it is released. But when JTAG is used, it is assigned to JTDO.

*Note:* By default, the TRACECLKIN input clock of the TPIU is tied to GND. It is assigned to HCLK two clock cycles after the bit TRACE\_IOEN has been set.

The debugger must then program the Trace Mode by writing the PROTOCOL[1:0] bits in the SPP\_R (Selected Pin Protocol) register of the TPIU.

- PROTOCOL=00: Trace Port Mode (synchronous)
- PROTOCOL=01 or 10: Serial Wire (Manchester or NRZ) Mode (asynchronous mode). Default state is 01

It then also configures the TRACE port size by writing the bits [3:0] in the CPSPS\_R (Current Sync Port Size Register) of the TPIU:

- 0x1 for 1 pin (default state)
- 0x2 for 2 pins
- 0x8 for 4 pins

### 23.17.3 TPUI formatter

The formatter protocol outputs data in 16-byte frames:

- seven bytes of data
- eight bytes of mixed-use bytes consisting of:
  - 1 bit (LSB) to indicate it is a DATA byte ('0) or an ID byte ('1).
  - 7 bits (MSB) which can be data or change of source ID trace.
- one byte of auxiliary bits where each bit corresponds to one of the eight mixed-use bytes:
  - if the corresponding byte was a data, this bit gives bit0 of the data.
  - if the corresponding byte was an ID change, this bit indicates when that ID change takes effect.

*Note:* Refer to the *ARM® CoreSight Architecture Specification v1.0 (ARM® IHI 0029B)* for further information

### 23.17.4 TPUI frame synchronization packets

The TPUI can generate two types of synchronization packets:

- The Frame Synchronization packet (or Full Word Synchronization packet)  
It consists of the word: 0x7F\_FF\_FF\_FF (LSB emitted first). This sequence can not occur at any other time provided that the ID source code 0x7F has not been used.  
It is output periodically **between** frames.  
In continuous mode, the TPA must discard all these frames once a synchronization frame has been found.
- The Half-Word Synchronization packet  
It consists of the half word: 0x7F\_FF (LSB emitted first).  
It is output periodically **between or within** frames.  
These packets are only generated in continuous mode and enable the TPA to detect that the TRACE port is in IDLE mode (no TRACE to be captured). When detected by the TPA, it must be discarded.

### 23.17.5 Transmission of the synchronization frame packet

There is no Synchronization Counter register implemented in the TPIU of the core. Consequently, the synchronization trigger can only be generated by the **DWT**. Refer to the registers DWT Control Register (bits SYNCTAP[11:10]) and the DWT Current PC Sampler Cycle Count Register.

The TPUI Frame synchronization packet (0x7F\_FF\_FF\_FF) is emitted:

- after each TPIU reset release. This reset is synchronously released with the rising edge of the TRACECLKIN clock. This means that this packet is transmitted when the



TRACE\_IOEN bit in the DBGMCU\_CFG register is set. In this case, the word 0x7F\_FF\_FF\_FF is not followed by any formatted packet.

- at each DWT trigger (assuming DWT has been previously configured). Two cases occur:
  - If the bit SYNENA of the ITM is reset, only the word 0x7F\_FF\_FF\_FF is emitted without any formatted stream which follows.
  - If the bit SYNENA of the ITM is set, then the ITM synchronization packets will follow (0x80\_00\_00\_00\_00\_00), formatted by the TPUI (trace source ID added).

### 23.17.6 Synchronous mode

The trace data output size can be configured to 4, 2 or 1 pin: TRACED(3:0)

The output clock is output to the debugger (TRACECK)

Here, TRACECLKIN is driven internally and is connected to HCLK only when TRACE is used.

*Note:* In this synchronous mode, it is not required to provide a stable clock frequency.

The TRACE I/Os (including TRACECK) are driven by the rising edge of TRACLKIN (equal to HCLK). Consequently, the output frequency of TRACECK is equal to HCLK/2.

### 23.17.7 Asynchronous mode

This is a low cost alternative to output the trace using only 1 pin: this is the asynchronous output pin TRACESWO. Obviously there is a limited bandwidth.

TRACESWO is multiplexed with JTDO when using the SW-DP pin. This way, this functionality is available in all STM32F401xB/C and STM32F401xD/E packages.

This asynchronous mode requires a constant frequency for TRACECLKIN. For the standard UART (NRZ) capture mechanism, 5% accuracy is needed. The Manchester encoded version is tolerant up to 10%.

### 23.17.8 TRACECLKIN connection inside the STM32F401xB/C and STM32F401xD/E

In the STM32F401xB/C and STM32F401xD/E, this TRACECLKIN input is internally connected to HCLK. This means that when in asynchronous trace mode, the application is restricted to use to time frames where the CPU frequency is stable.

*Note:* **Important:** when using asynchronous trace: it is important to be aware that:

*The default clock of the STM32F401xB/C and STM32F401xD/E MCUs is the internal RC oscillator. Its frequency under reset is different from the one after reset release. This is because the RC calibration is the default one under system reset and is updated at each system reset release.*

*Consequently, the trace port analyzer (TPA) should not enable the trace (with the TRACE\_IOEN bit) under system reset, because a Synchronization Frame Packet will be issued with a different bit time than trace packets which will be transmitted after reset release.*

### 23.17.9 TPIU registers

The TPIU APB registers can be read and written only if the bit TRCENA of the Debug Exception and Monitor Control Register (DEMCR) is set. Otherwise, the registers are read as zero (the output of this bit enables the PCLK of the TPIU).

**Table 149. Important TPIU registers**

Address	Register	Description
0xE0040004	Current port size	Allows the trace port size to be selected: Bit 0: Port size = 1 Bit 1: Port size = 2 Bit 2: Port size = 3, not supported Bit 3: Port Size = 4 Only 1 bit must be set. By default, the port size is one bit. (0x00000001)
0xE00400F0	Selected pin protocol	Allows the Trace Port Protocol to be selected: Bit1:0= 00: Sync Trace Port Mode 01: Serial Wire Output - manchester (default value) 10: Serial Wire Output - NRZ 11: reserved
0xE0040304	Formatter and flush control	Bits 31-9 = always '0 Bit 8 = TriglN = always '1 to indicate that triggers are indicated Bits 7-4 = always 0 Bits 3-2 = always 0 Bit 1 = EnFCont. In Sync Trace mode (Select_Pin_Protocol register bit1:0=00), this bit is forced to '1: the formatter is automatically enabled in continuous mode. In asynchronous mode (Select_Pin_Protocol register bit1:0 <> 00), this bit can be written to activate or not the formatter. Bit 0 = always 0 The resulting default value is 0x102 <b>Note:</b> In synchronous mode, because the TRACECTL pin is not mapped outside the chip, the formatter is always enabled in continuous mode -this way the formatter inserts some control packets to identify the source of the trace packets).
0xE0040300	Formatter and flush status	Not used in Cortex®-M4 with FPU, always read as 0x00000008

#### 23.17.10 Example of configuration

- Set the bit TRCENA in the Debug Exception and Monitor Control Register (DEMCR)
- Write the TPIU Current Port Size Register to the desired value (default is 0x1 for a 1-bit port size)
- Write TPIU Formatter and Flush Control Register to 0x102 (default value)
- Write the TPIU Select Pin Protocol to select the sync or async mode. Example: 0x2 for async NRZ mode (UART like)
- Write the DBGMCU control register to 0x20 (bit IO\_TRACEN) to assign TRACE I/Os for async mode. A TPIU Sync packet is emitted at this time (FF\_FF\_FF\_7F)
- Configure the ITM and write the ITM Stimulus register to output a value

### 23.18 DBG register map

The following table summarizes the Debug registers.

**Table 150. DBG register map and reset values**

Addr.	Register	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0		
0xE004 2000	DBGMCU_IDCODE	REV_ID															Reserved			DEV_ID															
	Reset value <sup>(1)</sup>	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X					X	X	X	X	X	X	X	X	X	X	X	X		
0xE004 2004	DBGMCU_CR	Reserved															DBG_TIM5_STOP	Reserved		Reserved									TRACE_MODE[1:0]	TRACE_IOEN	Reserved		DBG_STANDBY	DBG_STOP	DBG_SLEEP
	Reset value																0												0	0	0			0	0
0xE004 2008	DBGMCU_APB1_FZ	Reserved									DBG_I2C3_SMBUS_TIMEOUT	DBG_I2C2_SMBUS_TIMEOUT	DBG_I2C1_SMBUS_TIMEOUT	Reserved						DBG_IWDG_STOP	DBG_WWDG_STOP	Reserved		DBG_RTC_STOP	Reserved										
	Reset value										0	0	0							0	0			0											
0xE004 200C	DBGMCU_APB2_FZ	Reserved															DBG_TIM11_STOP	DBG_TIM10_STOP	DBG_TIM9_STOP	Reserved															
	Reset value																0	0	0															0	

1. The reset value is product dependent. For more information, refer to [Section 23.6.1: MCU device ID code](#).



## 24 Device electronic signature

The electronic signature is stored in the Flash memory area. It can be read using the JTAG/SWD or the CPU. It contains factory-programmed identification data that allow the user firmware or other external devices to automatically match its interface to the characteristics of the STM32F4xx microcontrollers.

### 24.1 Unique device ID register (96 bits)

The unique device identifier is ideally suited:

- for use as serial numbers (for example USB string serial numbers or other end applications)
- for use as security keys in order to increase the security of code in Flash memory while using and combining this unique ID with software cryptographic primitives and protocols before programming the internal Flash memory
- to activate secure boot processes, etc.

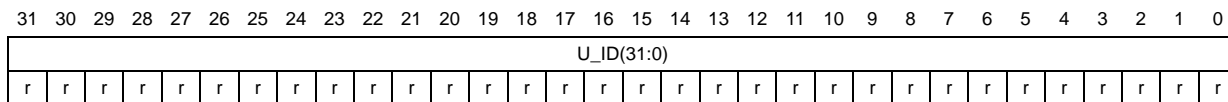
The 96-bit unique device identifier provides a reference number which is unique for any device and in any context. These bits can never be altered by the user.

The 96-bit unique device identifier can also be read in single bytes/half-words/words in different ways and then be concatenated using a custom algorithm.

**Base address: 0x1FFF 7A10**

Address offset: 0x00

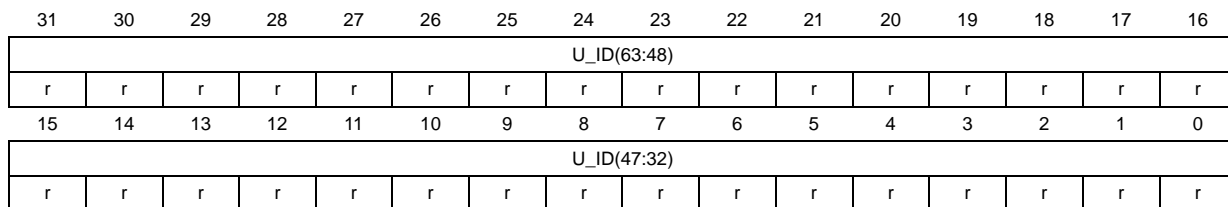
Read only = 0xXXXX XXXX where X is factory-programmed



Bits 31:0 **U\_ID(31:0)**: 31:0 unique ID bits

Address offset: 0x04

Read only = 0xXXXX XXXX where X is factory-programmed

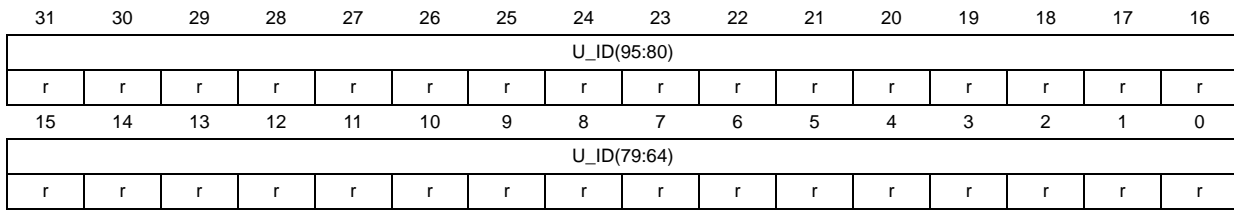


Bits 31:0 **U\_ID(63:32)**: 63:32 unique ID bits



Address offset: 0x08

Read only = 0xXXXX XXXX where X is factory-programmed



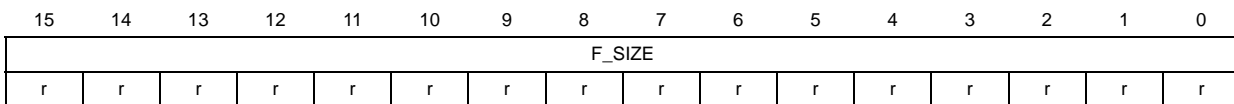
Bits 31:0 **U\_ID(95:64)**: 95:64 Unique ID bits.

## 24.2 Flash size

Base address: 0x1FFF 7A22

Address offset: 0x00

Read only = 0xXXXX where X is factory-programmed



Bits 15:0 **F\_ID(15:0)**: Flash memory size

This bitfield indicates the size of the device Flash memory expressed in Kbytes.  
As an example, 0x0400 corresponds to 1024 Kbytes.

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## Revision history

**Table 151. Document revision history**

Date	Version	Changes
07-Oct-2013	1	Initial release.
30-Jan-2014	2	<p>Added information for STM32F401xD/E devices throughout the manual</p> <p>Added <a href="#">Table 4: Memory mapping vs. Boot mode/physical remap in STM32F401xD/E</a></p> <p>Updated <a href="#">Table 5: Flash module organization (STM32F401xB/C and STM32F401xD/E)</a></p> <p>Updated <a href="#">Section 3.8.5: Flash control register (FLASH_CR)</a></p> <p>Updated <a href="#">Section 3.8.6: Flash option control register (FLASH_OPTCR)</a></p> <p><b>TIM1:</b></p> <p>Updated <a href="#">Table 50: TIMx Internal trigger connection</a></p> <p><b>TIM9 to TIM11:</b></p> <p>Added <a href="#">Table 57: TIMx internal trigger connection on page 392</a></p> <p><b>DMA:</b></p> <p>Modified <a href="#">Section 9.2: DMA main features</a></p> <p>Removed sentence in <a href="#">Section 9.3.7: Pointer incrementation</a></p> <p>Removed note in <a href="#">Section 9.3.11: Single and burst transfers</a></p> <p><b>Interrupts:</b></p> <p>Updated Description of MemManage exception in <a href="#">Table 38: Vector table for STM32F401xB/CSTM32F401xD/E on page 201</a></p> <p><b>RTC:</b></p> <p>Corrected name of bit 9 in <a href="#">Section 17.6.3: RTC control register (RTC_CR)</a></p> <p>Modified <a href="#">Section 17.3.11: RTC smooth digital calibration</a></p> <p><b>I2C:</b></p> <p>Changed acronyms for Standard mode and Fast mode to Sm and Fm in <a href="#">Section 18: Inter-integrated circuit (I2C) interface</a></p> <p><b>DEBUG:</b></p> <p>Updated REV_ID in <a href="#">Section : DBGMCU_IDCODE</a>.</p>
03-June-2014	3	<p>Modified conditional text in <a href="#">Section : Mass Erase</a> . Note has been added.</p> <p>Updated <a href="#">Section 3.6: Option bytes</a></p>

**Table 151. Document revision history (continued)**

Date	Version	Changes
04-May-2015	4	<p><b>PWR:</b>  Updated <a href="#">Table 15: Low-power mode summary</a> to add Return from ISR as entry condition.  Added <a href="#">Section : Entering low-power mode</a> and <a href="#">Section : Exiting low-power mode</a>.  Updated <a href="#">Section : Entering Sleep mode</a>, <a href="#">Section : Exiting Sleep mode</a>, <a href="#">Table 16: Sleep-now entry and exit</a> and <a href="#">Table 17: Sleep-on-exit entry and exit</a>.  Updated <a href="#">Section : Entering Stop mode</a>, <a href="#">Section : Exiting Stop mode</a> and <a href="#">Table 19: Stop mode entry and exit</a>.  Updated <a href="#">Section : Entering Standby mode</a>, <a href="#">Section : Exiting Standby mode</a> and <a href="#">Table 20: Standby mode entry and exit</a>.  Standby mode entry sequence updated in <a href="#">Table 20: Standby mode entry and exit</a> to change WUF bit (PWR_CSR) to CWUF (PWR_CR).</p> <p><b>RCC:</b>  Changed access type for bits 24 and 25:31 of <a href="#">Section 6.3.18: RCC clock control &amp; status register (RCC_CSR)</a>.</p> <p><b>DMA:</b>  Updated description of FTH[1:0] bits in <a href="#">Section 9.5.10: DMA stream x FIFO control register (DMA_SxFCR) (x = 0..7)</a>.</p> <p><b>TIM1:</b>  Updated <a href="#">Table 50: TIMx Internal trigger connection</a>.  Added note related to slave clock in MMS bits of <a href="#">Section 12.4.2: TIM1 control register 2 (TIMx_CR2)</a>.  Updated SMS bit description in <a href="#">Section 12.4.3: TIM1 slave mode control register (TIMx_SMCR)</a> and added note related to slave clock.</p> <p><b>TIM2/5:</b>  Updated <a href="#">Table 54: TIMx internal trigger connection</a>.  Added note related to the slave timer clock in <a href="#">Section 13.3.15: Timer synchronization</a>.  Added note related to slave clock in MMS bits of <a href="#">Section 13.4.2: TIMx control register 2 (TIMx_CR2)</a>.  Updated SMS bit description in <a href="#">Section 13.4.3: TIMx slave mode control register (TIMx_SMCR)</a> and added note related to slave clock.  Register format changed to 32 bits instead of 16 in <a href="#">Section 13.4.10: TIMx counter (TIMx_CNT)</a> and <a href="#">Section 13.4.12: TIMx auto-reload register (TIMx_ARR)</a>.</p> <p><b>TIM10/11:</b>  Updated <a href="#">Table 57: TIMx internal trigger connection</a>.  Added <a href="#">Section 14.5.2: TIM10/11 Interrupt enable register (TIMx_DIER)</a>.</p>

Table 151. Document revision history (continued)

Date	Version	Changes
04-May-2015	4	<p><b>WWDG</b> Updated <a href="#">Figure 157: Watchdog block diagram</a> and <a href="#">Section 16.4: How to program the watchdog timeout</a>.</p> <p><b>WDGLS:</b> Updated note in 1. in <a href="#">Table 62: Min/max IWDG timeout period at 32 kHz (LSI)</a>.</p> <p><b>I2C:</b> Updated <code>FREQ[5:0]</code> bitfield description in <a href="#">Section 18.6.2: I2C Control register 2 (I2C_CR2)</a></p> <p><b>USART:</b> <i>Removed note related to <code>RXNEIE</code> in <a href="#">Section : Reception using DMA</a>.</i></p> <p><b>USB_OTG:</b> Updated description of <code>TRDT</code> bits in <a href="#">Section : OTG_FS USB configuration register (OTG_FS_GUSBCFG)</a> and added <a href="#">Table 131: TRDT values..</a></p> <p><b>DEBUG:</b> Updated <code>REV_ID</code> bits in <a href="#">Section : DBGMCU_IDCODE</a>. Removed <code>DB</code> bit <code>G_TIM8_STOP</code> in <a href="#">Section 23.16.5: Debug MCU APB2 Freeze register (DBGMCU_APB2_FZ)</a></p>

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# **Cyclone V Device Handbook**

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## **Volume 1: Device Overview and Datasheet**



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The chapters in this document, Cyclone V Device Handbook, were revised on the following dates. Where chapters or groups of chapters are available separately, part numbers are listed.

- Chapter 1. Overview for Cyclone V Device Family  
Revised: *February 2012*  
Part Number: *CV-51001-1.2*
  
- Chapter 2. Device Datasheet for Cyclone V Devices  
Revised: *February 2012*  
Part Number: *CV-51002-1.2*



Cyclone® V devices are designed to simultaneously accommodate the shrinking power consumption, cost, and time-to-market requirements; and the increasing bandwidth requirements for high-volume and cost-sensitive applications.

The Cyclone V devices are ideal for small form factor applications that are cost- and power-sensitive in the wireless, wireline, military, broadcast, industrial, consumer, and communications industries.

The Cyclone V device family is available in six variants:

- Cyclone V E—optimized for the lowest system cost and power requirement for a wide spectrum of general logic and digital signal processing (DSP) applications.
- Cyclone V GX—optimized for the lowest cost and power requirement for 614-megabits per second (Mbps) to 3.125-gigabits per second (Gbps) transceiver applications.
- Cyclone V GT—the FPGA industry’s lowest cost and lowest power requirement for 5-Gbps transceiver applications.
- Cyclone V SE—system-on-a-chip (SoC) FPGA with integrated Cyclone V FPGA and ARM®-based hard processor system (HPS).
- Cyclone V SX—SoC FPGA with integrated Cyclone V FPGA, ARM-based HPS, and 3.125-Gbps transceivers.
- Cyclone V ST—SoC FPGA with integrated Cyclone V FPGA, ARM-based HPS, and 5-Gbps transceivers.

The Cyclone V SoC FPGA variants feature an FPGA integrated with an HPS that consists of a dual-core ARM Cortex™-A9 MPCore™ processor, a rich set of peripherals, and a shared multiport SDRAM controller.

The Cyclone V device family provides the following key advantages:

- Up to 40% lower power consumption than the previous generation device—built on TSMC’s 28-nm low power (28LP) process and includes an abundance of hard intellectual properties (IP).
- Improved logic integration and differentiation capabilities—features a new 8-input adaptive logic module (ALM), up to 11.6 megabits (Mb) of dedicated memory, and variable-precision DSP blocks.
- Increased bandwidth capacity—a combined result of the new 3-Gbps and 5-Gbps transceivers, and the hard memory controllers.
- Tight integration of a dual-core ARM Cortex-A9 MPCore processor, hard IP, and an FPGA in a single Cyclone V SoC FPGA—supports over 100 Gbps peak bandwidth with integrated data coherency between the processor and the FPGA.

## Cyclone V Features Summary

Some of the key features of the Cyclone V devices include:

- Built-in hard IP blocks
- Support for all mainstream single-ended and differential I/O standards including 3.3 V at up to 16 mA drive strengths
- HPS for the Cyclone V SE, SX, and ST variants
- Comprehensive design protection features to protect your valuable IP investments
- Lowest system cost advantage—requires only two core voltages to operate, are available in low-cost wirebond packaging, and includes innovative cost saving features such as Configuration via Protocol (CvP) and partial reconfiguration

Table 1–1 lists a summary of the Cyclone V features.

**Table 1–1. Summary of Features for Cyclone V Devices (Part 1 of 2)**

Feature	Details	
Technology	<ul style="list-style-type: none"> <li>■ TSMC's 28-nm low power (28LP) process technology</li> <li>■ 1.1-V core voltage</li> </ul>	
Low-power high-speed serial interface	<ul style="list-style-type: none"> <li>■ 614 Mbps to 5.0 Gbps integrated transceiver speed</li> <li>■ Transmitter pre-emphasis and receiver equalization</li> <li>■ Dynamic partial reconfiguration of individual channels</li> </ul>	
FPGA General-purpose I/Os (GPIOs)	<ul style="list-style-type: none"> <li>■ 875 Mbps LVDS receiver and 840 Mbps LVDS transmitter</li> <li>■ 400 MHz/800 Mbps external memory interface</li> <li>■ On-chip termination (OCT)</li> <li>■ 3.3-V support with up to 16 mA drive strength</li> </ul>	
Hard IP blocks	Embedded transceiver I/O	PCI Express® (PCIe®) Gen2 (x1 or x2) and Gen1 (x1, x2, or x4) hard IP with multifunction support, endpoint, and root port
	Variable-precision DSP	<ul style="list-style-type: none"> <li>■ Native support for three signal processing precision levels (three 9 x 9s, two 18 x 19s, or one 27 x 27 multiplier) in the same variable-precision DSP block</li> <li>■ 64-bit accumulator and cascade</li> <li>■ Embedded internal coefficient memory</li> <li>■ Preadder/subtractor for improved efficiency</li> </ul>
	Memory controller	DDR3, DDR2, LPDDR, and LPDDR2

**Table 1-1. Summary of Features for Cyclone V Devices (Part 2 of 2)**

Feature	Details
HPS (Cyclone V SE, SX, and ST devices only)	<ul style="list-style-type: none"> <li>■ Dual-core ARM Cortex-A9 MPCore processor—up to 800 MHz maximum frequency with support for symmetric and asymmetric multiprocessing</li> <li>■ Interface peripherals—10/100/1000 Ethernet media access control (MAC), USB 2.0 On-The-Go (OTG) controller, serial peripheral interface (SPI), Quad SPI flash controller, NAND flash controller, SD/MMC/SDIO controller, UART, controller area network (CAN), I2C interface, and up to 71 HPS I/O interfaces</li> <li>■ System peripherals—general-purpose and watchdog timers, direct memory access (DMA) controller, FPGA configuration manager, and clock and reset managers</li> <li>■ On-chip RAM and boot ROM</li> <li>■ HPS-FPGA bridges—include the FPGA-to-HPS, HPS-to-FPGA, and lightweight HPS-to-FPGA bridges that allow the FPGA fabric to master transactions to slaves in the HPS, and vice versa.</li> <li>■ FPGA-to-HPS SDRAM controller subsystem—provides a configurable interface to the multiport front end (MPFE) of the HPS SDRAM controller</li> <li>■ ARM CoreSight™ JTAG debug access port, trace port, and on-chip trace storage</li> </ul>
High-performance FPGA fabric	Enhanced 8-input ALM with four registers
Internal memory blocks	<ul style="list-style-type: none"> <li>■ M10K—10-kilobits (Kb) memory blocks with soft error correction code (ECC)</li> <li>■ Memory logic array block (MLAB)—640-bit distributed LUTRAM where you can use up to 25% of the ALMs as MLAB memory</li> </ul>
Phase-locked loops (PLLs)	<ul style="list-style-type: none"> <li>■ Precision clock synthesis, clock delay compensation, and zero delay buffering (ZDB)</li> <li>■ Integer mode and fractional mode</li> </ul>
Clock networks	<ul style="list-style-type: none"> <li>■ 550 MHz global clock network</li> <li>■ Global, quadrant, and peripheral clock networks</li> <li>■ Clock networks that are not used can be powered down to reduce dynamic power</li> </ul>
Configuration	<ul style="list-style-type: none"> <li>■ Partial and dynamic reconfiguration of the FPGA</li> <li>■ CvP</li> <li>■ Active serial (AS) x1 and x4, fast passive parallel (FPP) x8 and x16, passive serial (PS), and JTAG options</li> <li>■ Enhanced advanced encryption standard (AES) design security features</li> <li>■ Tamper protection</li> </ul>
Packaging	<ul style="list-style-type: none"> <li>■ Wirebond low-halogen packages</li> <li>■ Multiple device densities with compatible package footprints for seamless migration between different device densities</li> <li>■ RoHS-compliant options</li> </ul>

## Cyclone V Family Plan

Table 1-2 and Table 1-3 list the Cyclone V E, GX, and GT maximum resource counts.

**Table 1-2. Maximum Resource Counts for Cyclone V E Devices—Preliminary**

Resource	Cyclone V E Device				
	5CEA2	5CEA4	5CEA5	5CEA7	5CEA9
ALM	9,434	18,113	28,868	56,415	113,585
Logic Element (LE)	25,000	48,000	76,500	149,500	301,000
Block Memory (Kb)	1,700	2,700	3,800	6,500	11,600
MLAB Memory (Kb)	196	270	440	836	1,717
Variable-precision DSP Block	25	72	124	156	342
18 x 19 Multiplier	50	144	248	312	684
Fractional PLL	4	4	6	6	6
GPIO	288	288	272	480	448
LVDS	100	100	100	122	122
Hard Memory Controller	1	1	2	2	2

**Table 1-3. Maximum Resource Counts for Cyclone V GX and GT Devices—Preliminary**

Resource	Cyclone V GX Device					Cyclone V GT Device		
	5CGXC3	5CGXC4	5CGXC5	5CGXC7	5CGXC9	5CGTD5	5CGTD7	5CGTD9
ALM	11,698	18,868	28,868	56,415	113,585	28,868	56,415	113,585
LE	31,000	50,000	76,500	149,500	301,000	76,500	149,500	301,000
Block Memory (Kb)	1,400	2,500	3,800	6,500	11,600	3,800	6,500	11,600
MLAB Memory (Kb)	147	295	440	836	1,717	440	836	1,717
Variable-precision DSP Block	42	70	124	156	342	124	156	342
18 x 19 Multiplier	84	140	248	312	684	248	312	684
Fractional PLL <sup>(1)</sup>	4	6	6	7	8	6	7	8
3-Gbps Transceiver	3	6	6	9	12	—	—	—
5-Gbps Transceiver	—	—	—	—	—	6	9	12
GPIO	224	368	368	480	560	368	480	560
LVDS	48	90	100	122	122	100	122	122
PCIe Hard IP Block	1	2	2	2	2	2	2	2
Hard Memory Controller	1	2	2	2	2	2	2	2

**Note to Table 1-3:**

(1) The maximum fractional PLLs listed include general purpose PLLs and transceiver PLLs.



Table 1-4 and Table 1-5 list the Cyclone V SE, SX, and ST maximum resource counts.

**Table 1-4. Maximum Resource Counts for Cyclone V SE Devices—Preliminary**

Resource	Cyclone V SE Devices			
	5CSEA2	5CSEA4	5CSEA5	5CSEA6
ALM	9,434	15,094	32,075	41,509
LE	25,000	40,000	85,000	110,000
Block Memory (Kb)	1,400	2,240	3,972	5,140
MLAB Memory (Kb)	138	220	480	621
Variable-precision DSP Block	36	58	87	112
18 x 19 Multiplier	72	116	174	224
FPGA Fractional PLL	4	5	6	6
HPS PLL	3	3	3	3
FPGA GPIO	124	124	288	288
HPS I/O	188	188	188	188
LVDS	31	31	72	72
FPGA Memory Controller	—	1	1	1
HPS Memory Controller	1	1	1	1
ARM Cortex-A9 MPCore Processor	Single- or dual-core	Single- or dual-core	Single- or dual-core	Single- or dual-core

**Table 1-5. Maximum Resource Counts for Cyclone V SX and ST Devices—Preliminary (Part 1 of 2)**

Resource	Cyclone V SX Device			Cyclone V ST Device	
	5CSXC4	5CSXC5	5CSXC6	5CSTD5	5CSTD6
ALM	15,094	32,075	41,509	32,075	41,509
LE	40,000	85,000	110,000	85,000	110,000
Block Memory (Kb)	2,240	3,972	5,140	3,972	5,140
MLAB Memory (Kb)	220	480	621	480	621
Variable-precision DSP Block	58	87	112	87	112
18 x 19 Multiplier	116	174	224	174	224
FPGA Fractional PLL <sup>(1)</sup>	5	6	6	6	6
HPS PLL	3	3	3	3	3
3-Gbps Transceiver	6	9	9	—	—
5-Gbps Transceiver	—	—	—	9	9
FPGA GPIO	124	288	288	288	288
HPS I/O	188	188	188	188	188
LVDS	31	72	72	72	72

**Table 1-5. Maximum Resource Counts for Cyclone V SX and ST Devices—Preliminary (Part 2 of 2)**

Resource	Cyclone V SX Device			Cyclone V ST Device	
	5CSXC4	5CSXC5	5CSXC6	5CSTD5	5CSTD6
PCIe Hard IP Block	2	2	2	2	2
FPGA Memory Controller	1	1	1	1	1
HPS Memory Controller	1	1	1	1	1
ARM Cortex-A9 MPCore Processor	Dual-core	Dual-core	Dual-core	Dual-core	Dual-core

**Note to Table 1-5:**

(1) The maximum FPGA fractional PLLs listed include FPGA general purpose PLLs and transceiver PLLs.

Table 1-6 lists the Cyclone V E, GX, and GT package plan that shows the GPIO count, the maximum number of transceivers available, and the vertical migration capability for each device package and density.

**Table 1-6. Package Plan for Cyclone V E, GX, and GT Devices—Preliminary<sup>(1)</sup>**

Device	F256 (17 mm)		U324 (15 mm)		U484 (19 mm)		F484 (23 mm)		F672 (27 mm)		F896 (31 mm)		F1152 (35 mm)	
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR
5CEA2	▲144	—	▲176	—	▲288	—	▲288	—	—	—	—	—	—	—
5CEA4	▼144	—	▼176	—	▲288	—	▲288	—	—	—	—	—	—	—
5CEA5	—	—	—	—	▼272	—	▼272	—	—	—	—	—	—	—
5CEA7	—	—	—	—	240	—	▲240	—	▲336	—	▲480	—	—	—
5CEA9	—	—	—	—	—	—	▼224	—	▼336	—	▼448	—	—	—
5CGXC3 <sup>(2)</sup>	—	—	112	3	▲208	3	▲208	3	—	—	—	—	—	—
5CGXC4 <sup>(2)</sup>	—	—	—	—	224	6	▲240	6	▲336	6	—	—	—	—
5CGXC5 <sup>(2)</sup>	—	—	—	—	224	6	▲240	6	▲336	6	—	—	—	—
5CGXC7 <sup>(2)</sup>	—	—	—	—	▼240	6	▲240	6	▲336	9	▲480	9	—	—
5CGXC9 <sup>(2)</sup>	—	—	—	—	—	—	▼224	6	▼336	9	▼448	12	560	12
5CGTD5 <sup>(3)</sup>	—	—	—	—	▲240	6	▲240	6	▲368	6	—	—	—	—
5CGTD7 <sup>(3)</sup>	—	—	—	—	▼240	6	▲240	6	▲336	9	▲480	9	—	—
5CGTD9 <sup>(3)</sup>	—	—	—	—	—	—	▼224	6	▼336	9	▼448	12	560	12

**Notes to Table 1-6:**

- (1) The arrows indicate the package vertical migration capability. You can also migrate your design across device densities in the same packaging option if the devices have the same dedicated pins, configuration pins, and power pins.
- (2) The transceiver counts listed are for 3-Gbps transceivers.
- (3) The transceiver counts listed are for 5-Gbps transceivers.

Table 1-7 lists the Cyclone V SE, SX, and ST package plan that shows the FPGA GPIO and HPS I/O counts, the maximum number of transceivers available, and the vertical migration capability for each device package and density.

**Table 1-7. Package Plan for Cyclone V SE, SX, and ST Devices—Preliminary<sup>(1)</sup>**

Device	U484 (19 mm)			U672 (23 mm)			F896 (31 mm)		
	GPIO	XCVR	HPS I/O	GPIO	XCVR	HPS I/O	GPIO	XCVR	HPS I/O
5CSEA2	▲ 66	—	161	▲ 124	—	188	—	—	—
5CSEA4	▲ 66	—	161	▼ 124	—	188	—	—	—
5CSEA5	▲ 66	—	161	▲ 124	—	188	▲ 288	—	188
5CSEA6	▼ 66	—	161	▼ 124	—	188	▼ 288	—	188
5CSXC4 <sup>(2)</sup>	—	—	—	124	6	188	—	—	—
5CSXC5 <sup>(2)</sup>	—	—	—	▲ 124	6	188	▲ 288	9	188
5CSXC6 <sup>(2)</sup>	—	—	—	▼ 124	6	188	▼ 288	9	188
5CSTD5 <sup>(3)</sup>	—	—	—	—	—	—	▲ 288	9	188
5CSTD6 <sup>(3)</sup>	—	—	—	—	—	—	▼ 288	9	188

**Notes to Table 1-7:**

- (1) The arrows indicate the package vertical migration capability. You can also migrate your design across device densities in the same packaging option if the devices have the same dedicated pins, configuration pins, and power pins.
- (2) The transceiver counts listed are for 3-Gbps transceivers.
- (3) The transceiver counts listed are for 5-Gbps transceivers.



To verify the pin migration compatibility, use the Pin Migration View window in the Quartus II software Pin Planner.

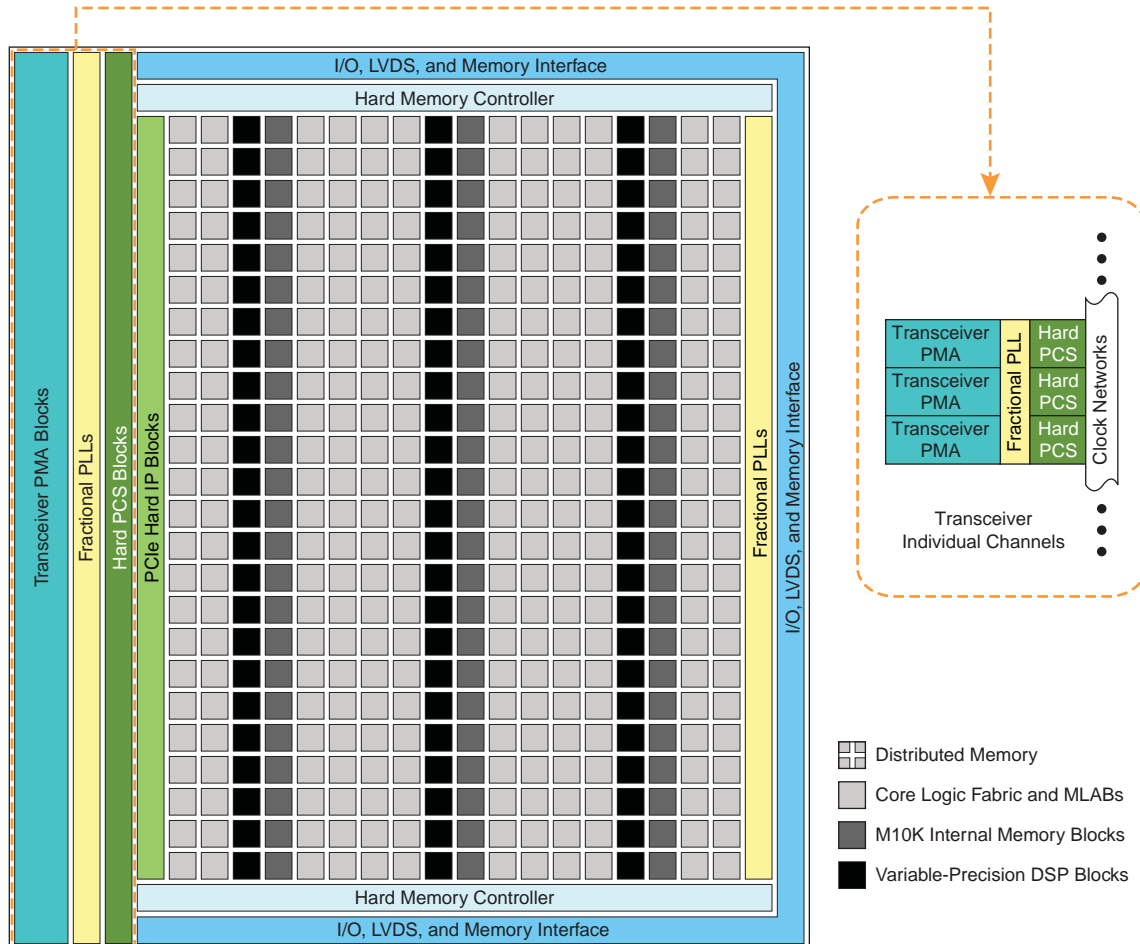


For more information about the verifying the pin migration compatibility, refer to the “I/O Management” chapter in the *Quartus II Handbook*.

## Low-Power Serial Transceivers

Cyclone V devices deliver the industry's lowest power 5-Gbps transceivers at an estimated 88 mW maximum power consumption per channel. Cyclone V transceivers are designed to be compliant for a wide range of protocols and data rates. The transceivers are positioned on the left outer edge of the device, as shown in Figure 1-1. The transceiver channels consist of the physical medium attachment (PMA), physical coding sublayer (PCS), and clock networks.

**Figure 1-1. Device Chip Overview for Cyclone V GX and GT Devices <sup>(1)</sup>**



**Note to Figure 1-1:**

(1) This figure represents a Cyclone V device with transceivers. Other Cyclone V devices may have a different floor plan than the one shown here.

## PMA Support

To prevent core and I/O noise from coupling into the transceivers, the PMA block is isolated from the rest of the chip—ensuring optimal signal integrity. For the transceivers, you can use the channel PLL of an unused receiver PMA as an additional transmit PLL.

Table 1-8 lists the PMA features of the transceiver.

**Table 1-8. PMA Features of the Transceivers in Cyclone V Devices**

Features	Capability
Backplane support	Up to 16" FR4 PCB fabric drive capability at up to 5 Gbps
PLL-based clock recovery	Superior jitter tolerance
Programmable deserialization and word alignment	Flexible deserialization width and configurable word alignment pattern
Equalization and pre-emphasis	Up to 6 dB of pre-emphasis, up to 4 dB of equalization, and no decision feedback equalizer (DFE)
Ring oscillator transmit PLLs	614 Mbps to 5 Gbps
Input reference clock range	20 MHz to 400 MHz
Transceiver dynamic reconfiguration	Allows the reconfiguration of a single channel without affecting the operation of other channels

## PCS Support

The Cyclone V core logic connects to the PCS through an 8-, 10-, 16-, 20-, 32-, or 40-bit interface, depending on the transceiver data rate and protocol. Cyclone V devices contain PCS hard IP to support PCIe Gen1 and Gen2, XAUI, Gbps Ethernet (GbE), Serial RapidIO® (SRIO), and Common Public Radio Interface (CPRI). Most of the other standard and proprietary protocols from 614 Mbps to 5.0 Gbps are supported.

Table 1-9 lists the PCS features of the transceiver.

**Table 1-9. PCS Features of the Transceivers in Cyclone V Devices (Part 1 of 2)**

PCS Support	Data Rates (Gbps)	Transmitter Datapath	Receiver Datapath
3-Gbps and 5-Gbps Basic	0.614 to 5.0	<ul style="list-style-type: none"> <li>■ Phase compensation FIFO</li> <li>■ Byte serializer</li> <li>■ 8B/10B encoder</li> <li>■ Transmitter bit-slip</li> </ul>	<ul style="list-style-type: none"> <li>■ Word aligner</li> <li>■ Deskew FIFO</li> <li>■ Rate-match FIFO</li> <li>■ 8B/10B decoder</li> <li>■ Byte deserializer</li> <li>■ Byte ordering</li> <li>■ Receiver phase compensation FIFO</li> </ul>
PCIe Gen1: x1, x2, x4 PCIe Gen2: x1, x2 <sup>(1)</sup>	2.5 and 5.0	<ul style="list-style-type: none"> <li>■ Dedicated PCIe PHY IP core</li> <li>■ PIPE 2.0 interface to the core logic</li> </ul>	<ul style="list-style-type: none"> <li>■ Dedicated PCIe PHY IP core</li> <li>■ PIPE 2.0 interface to the core logic</li> </ul>
GbE	1.25	<ul style="list-style-type: none"> <li>■ Custom PHY IP core with preset feature</li> <li>■ GbE transmitter synchronization state machine</li> </ul>	<ul style="list-style-type: none"> <li>■ Custom PHY IP core with preset feature</li> <li>■ GbE receiver synchronization state machine</li> </ul>

**Table 1-9. PCS Features of the Transceivers in Cyclone V Devices (Part 2 of 2)**

PCS Support	Data Rates (Gbps)	Transmitter Datapath	Receiver Datapath
XAUI	3.125	<ul style="list-style-type: none"> <li>■ Dedicated XAUI PHY IP core</li> <li>■ XAUI synchronization state machine for bonding four channels</li> </ul>	<ul style="list-style-type: none"> <li>■ Dedicated XAUI PHY IP core</li> <li>■ XAUI synchronization state machine for realigning four channels</li> </ul>
SRIO 1.3 and 2.1	1.25 to 3.125	<ul style="list-style-type: none"> <li>■ Custom PHY IP core with preset feature</li> <li>■ SRIO version 2.1-compliant x2 and x4 channel bonding</li> </ul>	<ul style="list-style-type: none"> <li>■ Custom PHY IP core with preset feature</li> <li>■ SRIO version 2.1-compliant x2 and x4 deskew state machine</li> </ul>
SDI, SD/HD, and 3G-SDI	0.27 <sup>(2)</sup> , 1.485, and 2.97	<ul style="list-style-type: none"> <li>■ Custom PHY IP core with preset feature</li> </ul>	<ul style="list-style-type: none"> <li>■ Custom PHY IP core with preset feature</li> </ul>
Serial ATA Gen1 and Gen2	1.5 and 3.0	<ul style="list-style-type: none"> <li>■ Custom PHY IP core with preset feature</li> <li>■ Electrical idle</li> </ul>	<ul style="list-style-type: none"> <li>■ Custom PHY IP core with preset feature</li> <li>■ Signal detect</li> <li>■ Wider spread of asynchronous SSC</li> </ul>
CPRI 4.1 <sup>(3)</sup>	0.6144 to 4.9152	<ul style="list-style-type: none"> <li>■ Dedicated deterministic latency PHY IP core</li> <li>■ Transmitter (TX) manual bit-slip mode</li> </ul>	<ul style="list-style-type: none"> <li>■ Dedicated deterministic latency PHY IP core</li> <li>■ Receiver (RX) deterministic latency state machine</li> </ul>
OBSAI RP3	0.768 to 3.072	<ul style="list-style-type: none"> <li>■ Dedicated deterministic latency PHY IP core</li> <li>■ TX manual bit-slip mode</li> </ul>	<ul style="list-style-type: none"> <li>■ Dedicated deterministic latency PHY IP core</li> <li>■ RX deterministic latency state machine</li> </ul>
V-by-One HS	Up to 3.75	Custom PHY IP core	<ul style="list-style-type: none"> <li>■ Custom PHY IP core</li> <li>■ Wider spread of asynchronous SSC</li> </ul>
DisplayPort 1.2 <sup>(4)</sup>	1.62 and 2.7	Custom PHY IP core	<ul style="list-style-type: none"> <li>■ Custom PHY IP core</li> <li>■ Wider spread of asynchronous SSC</li> </ul>
HiGig	3.75	<ul style="list-style-type: none"> <li>■ Dedicated XAUI PHY IP core</li> <li>■ XAUI synchronization state machine for bonding four channels</li> </ul>	<ul style="list-style-type: none"> <li>■ Dedicated XAUI PHY IP core</li> <li>■ XAUI synchronization state machine for realigning four channels</li> </ul>
JESD204A	0.3125 <sup>(2)</sup> to 3.125	Custom PHY IP core with preset feature	Custom PHY IP core with preset feature

**Notes to Table 1-9:**

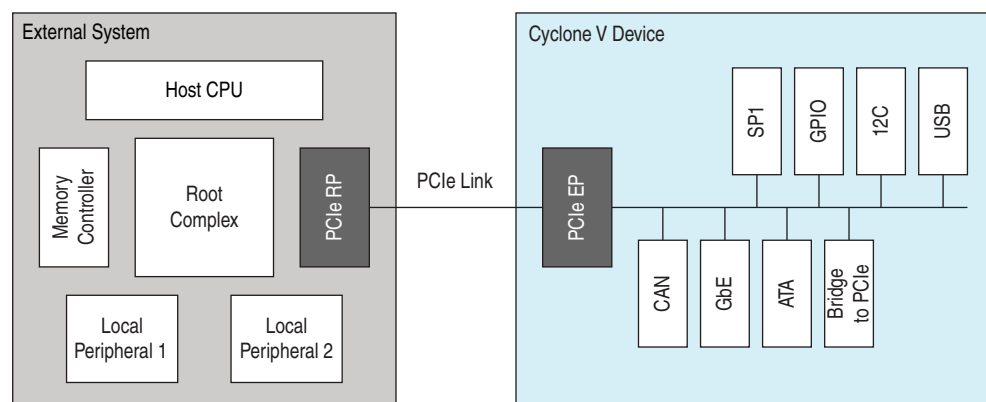
- (1) PCIe Gen2 is supported only for Cyclone V GT devices.
- (2) The 0.27-Gbps and 0.3125-Gbps data rates are supported using oversampling user logic that you must implement in the FPGA fabric.
- (3) High-voltage output mode (1000-BASE-CX) is not supported.
- (4) Pending characterization.

## PCIe Gen1 and Gen2 Hard IP

Cyclone V GX, GT, SX, and ST devices contain PCIe hard IP—consisting of the MAC, data link, and transaction layers—that is designed for performance, ease-of-use, and increased functionality. The PCIe hard IP supports PCIe Gen2 end point and root port for x1 and x2 lanes configuration, and Gen1 end point and root port for up to x4 lane configuration.

The PCIe endpoint support includes multifunction support for up to eight functions, as shown in Figure 1-2. The integrated multifunction support reduces the FPGA logic requirements by up to 20 K LEs for PCIe designs that require multiple peripherals.

**Figure 1-2. PCIe Multifunction for Cyclone V Devices**



The Cyclone V PCIe hard IP operates independently from the core logic. This independent operation allows the PCIe link to wake up and complete link training in less than 100 ms while the Cyclone V device completes loading the programming file for the rest of the device. In addition, the PCIe hard IP in the Cyclone V device provides improved end-to-end datapath protection using ECC.

## FPGA GPIOs

Cyclone V devices offer highly configurable GPIOs. The following list describes the many features of the GPIOs:

- Programmable bus hold and weak pull-up.
- LVDS output buffer with programmable differential output voltage ( $V_{OD}$ ) and programmable pre-emphasis.
- Dynamic on-chip parallel termination ( $R_T$  OCT) for all I/O banks with OCT calibration to limit the termination impedance variation to  $\pm 15\%$ .
- On-chip dynamic termination that has the ability to swap between serial and parallel termination, depending on whether there is read or write on a common bus for signal integrity.
- Unused voltage reference ( $V_{REF}$ ) pins that can be configured as user I/Os.
- Easy timing closure support using the hard read FIFO in the input register path, and delay-locked loop (DLL) delay chain with fine and coarse architecture.

## External Memory

Cyclone V devices support up to two hard memory controllers for DDR3, DDR2, LPDDR2, and LPDDR SDRAM devices. Each controller supports 8- to 32-bit components of up to 4 gigabits (Gb) in density with two chip selects and optional ECC. Cyclone V devices also support soft memory controllers for DDR3, DDR2, LPDDR2, and LPDDR SDRAM for maximum flexibility.

Table 1-10 lists the performance of the external memory interface in Cyclone V devices.

**Table 1-10. External Memory Interface Performance in Cyclone V Devices**

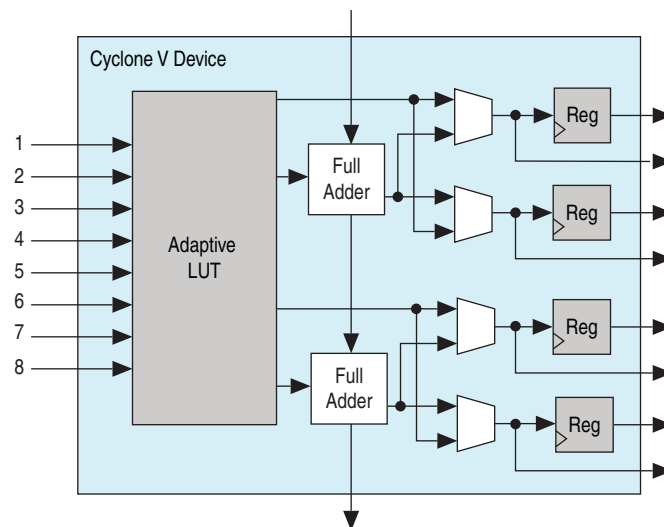
Interface	Voltage (V)	Hard Controller (MHz)	Soft Controller (MHz)
DDR3 SDRAM	1.5	400	300
DDR3L SDRAM	1.35	400	300
DDR3U SDRAM	1.25	333	300
DDR2 SDRAM	1.8	400	300
	1.5	400	300
LPDDR2 SDRAM	1.2	333	300
LPDDR SDRAM	1.8	200	200

## Adaptive Logic Module

Cyclone V devices use a 28-nm ALM as the basic building block of the logic fabric. The ALM, as shown in Figure 1-3, uses an 8-input fracturable look-up table (LUT) with four dedicated registers to help improve timing closure in register-rich designs and achieve an even higher design packing capability than previous generations.

You can configure up to 25% of the ALMs in Cyclone V devices as distributed memory using MLABs. For more information, refer to “[Embedded Memory](#)” on page 1-14.

**Figure 1-3. ALM for Cyclone V Devices**





## Variable-Precision DSP Block

Cyclone V devices feature a variable-precision DSP block that you can configure to support signal processing with precisions ranging from 9 x 9, 18 x 19, and 27 x 27 bits natively.

You can configure each DSP block during compilation as independent three 9 x 9, two 18 x 19, or one 27 x 27 multipliers. With a dedicated 64-bit cascade bus, you can cascade multiple variable-precision DSP blocks to implement even higher precision DSP functions efficiently.

The variable-precision DSP block also supports these features:

- A 64-bit accumulator that is the largest in the industry.
- A hard preadder that is available in both 18- and 27-bit modes.
- Cascaded output adders for efficient systolic finite impulse response (FIR) filters.
- Internal coefficient register banks, 8 deep, for each multiplier in 18- or 27-bit mode.
- Fully independent multiplier operation.
- A second accumulator feedback register to accommodate complex multiply-accumulate functions.
- Efficient support for single- and double-precision floating point arithmetic.
- The inferability of all modes by the Quartus® II design software.

Table 1-11 lists the relevant DSP block configurations for a few usage examples.

**Table 1-11. Variable-Precision DSP Block Configurations for Cyclone V Devices**

Usage	Multiplier Size (Bit)	DSP Block Resource
Low precision fixed point for video applications	Three 9 x 9	1 variable-precision DSP block
Medium precision fixed point in FIR filters	Two 18 x 19	1 variable-precision DSP block
FIR filters and general DSP usage	Two 18 x 19 with accumulate	1 variable-precision DSP block
High precision fixed- or floating-point implementations	One 27 x 27 with accumulate	1 variable-precision DSP block

Table 1-12 lists the variable-precision DSP resources by bit precision for each Cyclone V device.

**Table 1-12. Number of Multipliers in Cyclone V Devices (Part 1 of 2)**

Variant	Device	Variable-precision DSP Block	Independent Input and Output Multiplications Operator			18 x 19 Multiplier Adder Mode	18 x 18 Multiplier Adder Summed with 36-bit Input
			9 x 9 Multiplier	18 x 19 Multiplier	27 x 27 Multiplier		
Cyclone V E	5CEA2	25	75	50	25	25	25
	5CEA4	72	216	144	72	72	72
	5CEA5	124	372	248	124	124	124
	5CEA7	156	468	312	156	156	156
	5CEA9	342	1,026	684	342	342	342

**Table 1–12. Number of Multipliers in Cyclone V Devices (Part 2 of 2)**

Variant	Device	Variable-precision DSP Block	Independent Input and Output Multiplications Operator			18 x 19 Multiplier Adder Mode	18 x 18 Multiplier Adder Summed with 36-bit Input
			9 x 9 Multiplier	18 x 19 Multiplier	27 x 27 Multiplier		
Cyclone V GX	5CGXC3	42	126	84	42	42	42
	5CGXC4	70	210	140	70	70	70
	5CGXC5	124	372	248	124	124	124
	5CGXC7	156	468	312	156	156	156
	5CGXC9	342	1,026	684	342	342	342
Cyclone V GT	5CGTD5	124	372	248	124	124	124
	5CGTD7	156	468	312	156	156	156
	5CGTD9	342	1,026	684	342	342	342
Cyclone V SE	5CSEA2	36	108	73	36	36	36
	5CSEA4	58	174	116	58	58	58
	5CSEA5	87	261	173	87	87	87
	5CSEA6	112	336	224	112	112	112
Cyclone V SX	5CSXC4	36	108	73	36	36	36
	5CSXC5	58	174	116	58	58	58
	5CSXC6	87	261	173	87	87	87
Cyclone V ST	5CSTD5	87	261	173	87	87	87
	5CSTD6	112	336	224	112	112	112

## Embedded Memory

The Cyclone V embedded memory blocks are flexible and designed to provide an optimal amount of small- and large-sized memory arrays. Cyclone V devices contain two types of embedded memory blocks:

- 640-bit MLAB blocks—ideal for wide and shallow memory arrays. The MLAB operates at up to 300 MHz.
- 10-Kb M10K blocks—ideal for larger memory arrays while still providing a large number of independent ports. The M10K embedded memory operates at up to 380 MHz.

Table 1-13 lists the supported memory configurations for Cyclone V devices.

**Table 1-13. Embedded Memory Block Configurations for Cyclone V Devices**

Memory Block	Depth (bits)	Programmable Widths
MLAB	32	x1, x2, x4, x8, x9, x10, x16, x18, or x20
M10K	256	x40 or x32
	512	x20 or x16
	1K	x10 or x8
	2K	x5 or x4
	4K	x2
	8K	x1

## Dynamic and Partial Reconfiguration

The dynamic reconfiguration feature allows you to dynamically change the transceiver data rates, PMA settings, or protocols of a channel, without affecting data transfer on adjacent channels. This feature is ideal for applications that require on-the-fly multiprotocol or multirate support. You can reconfigure the PMA and PCS blocks with dynamic reconfiguration.

Partial reconfiguration allows you to reconfigure part of the device while other sections of the device remain operational. This capability is important in systems with critical uptime requirements because it allows you to make updates or adjust functionality without disrupting services.

Apart from lowering cost and power consumption, partial reconfiguration increases the effective logic density of the device because placing device functions that do not operate simultaneously is not necessary. Instead, you can store these functions in external memory and load them whenever the functions are required. This capability reduces the size of the device because it allows multiple applications on a single device—saving the board space and reducing the power consumption.

Altera simplifies the time-intensive task of partial reconfiguration by building this capability on top of the proven incremental compile and design flow in the Quartus II design software. With the Altera® solution, you do not need to know all the intricate device architecture details to perform a partial reconfiguration.

Partial reconfiguration is supported through the FPP x16 configuration interface. You can seamlessly use partial reconfiguration in tandem with dynamic reconfiguration to enable simultaneous partial reconfiguration of both the device core and transceivers.

## Clock Networks and PLL Clock Sources

The Cyclone V clock network architecture is based on Altera’s proven global, quadrant, and peripheral clock structure, which is supported by dedicated clock input pins and fractional PLLs. Cyclone V devices have 16 global clock networks capable of up to 550 MHz operation. The Quartus II software identifies all unused sections of the clock network and powers them down, which reduces power consumption.

Cyclone V devices have up to eight PLLs, each with nine output counters that you can use to reduce PLL usage in two ways:

- Reduce the number of oscillators that are required on your board by using fractional PLLs.
- Reduce the number of clock pins that are used in the device by synthesizing multiple clock frequencies from a single reference clock source.

Cyclone V devices use a fractional PLL architecture in addition to the historical integer PLL. If you use the fractional PLL mode, you can use the PLLs for precision fractional-N frequency synthesis—removing the need for off-chip reference clock sources in your design. The transceiver fractional PLLs that are not used by the transceiver I/Os can be used as general purpose fractional PLLs by the FPGA fabric.

Apart from frequency synthesis, on-chip clock deskew, jitter attenuation, counter reconfiguration, programmable output clock duty cycles, PLL cascading, and reference clock switchover, the PLLs in the Cyclone V devices also support the following key features:

- Programmable bandwidth
- User-mode reconfiguration of PLLs
- Low power mode for each fractional PLL
- Reference clock switchover
- Dynamic phase shift
- Direct, source synchronous, ZDB, external feedback, and LVDS compensation

## Enhanced Configuration and Configuration via Protocol

Cyclone V devices support 3.3-V programming voltage and several configuration modes. Table 1-14 lists the configuration modes and features supported by the Cyclone V devices.

**Table 1-14. Configuration Modes and Features for Cyclone V Devices**

Mode	Data Width (Bit)	Maximum Clock Rate (MHz)	Maximum Data Rate (Mbps)	Decompression	Design Security	Remote System Update	Partial Reconfiguration
AS through the EPCS and EPCQ serial configuration device	x1, x4	80	—	✓	✓	✓	—
PS through CPLD or external microcontroller	x1	125	125	✓	✓	—	—
FPP	x8, x16	125	—	✓	✓	Parallel flash loader	16-bit only
CvP (PCIe)	x1, x2, x4 (1)	—	—	—	✓	✓	✓
JTAG	x1	33	33	—	—	—	—

**Note to Table 1-14:**

(1) The number of lanes instead of bit.

Instead of using an external flash or ROM, you can configure the Cyclone V devices through PCIe using CvP. The CvP mode offers the fastest configuration rate and flexibility with the easy-to-use PCIe hard IP block interface. The Cyclone V CvP implementation conforms to the PCIe 100 ms power-up-to-active time requirement.

## Power Management

Leveraging the FPGA architectural features, process technology advancements, and transceivers that are designed for power efficiency, the Cyclone V devices consume less power than previous generation Cyclone FPGAs:

- Total device core power consumption—less by up to 40%.
- Transceiver channel power consumption—less by up to 50%.

Additionally, Cyclone V devices contain several hard IP blocks that reduce logic resources and deliver substantial power savings of up to 25% less power than equivalent soft implementations.

## SoC FPGA with HPS

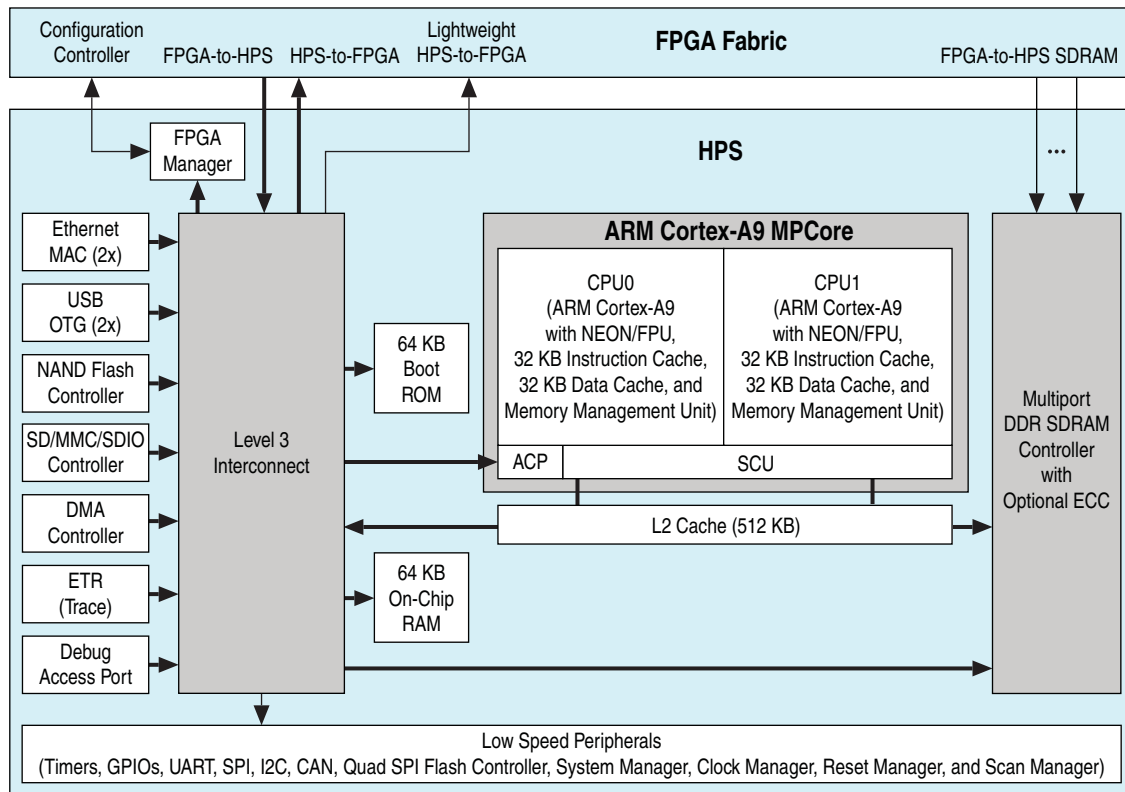
Each SoC FPGA combines an FPGA fabric and an HPS in a single device. This combination delivers the flexibility of programmable logic with the power and cost savings of hard IP in these ways:

- Reduces board space, system power, and bill of materials cost by eliminating a discrete embedded processor
- Allows you to differentiate the end product in both hardware and software, and to support virtually any interface standard
- Extends the product life and revenue through in-field hardware and software updates

## Features of the HPS

The HPS consists of a dual-core ARM Cortex-A9 MPCore processor, a rich set of peripherals, and a shared multiport SDRAM memory controller, as shown in Figure 1-4.

Figure 1-4. HPS with Dual-Core ARM Cortex-A9 MPCore Processor



## System Peripherals

Each Ethernet MAC, USB OTG, NAND flash controller, and SD/MMC/SDIO controller module has an integrated DMA controller. For modules without an integrated DMA controller, an additional DMA controller module provides up to eight channels of high-bandwidth data transfers. The debug access port provides interfaces to industry standard JTAG debug probes and supports ARM CoreSight debug and core traces to facilitate software development.

## HPS–FPGA AXI Bridges

The HPS–FPGA bridges, which support the Advanced Microcontroller Bus Architecture (AMBA<sup>®</sup>) Advanced eXtensible Interface (AXI<sup>™</sup>) specifications, consist of the following bridges:

- FPGA-to-HPS AXI bridge—a high-performance bus supporting 32-, 64-, and 128-bit data widths that allows the FPGA fabric to master transactions to the slaves in the HPS
- HPS-to-FPGA AXI bridge—a high-performance bus supporting 32-, 64-, and 128-bit data widths that allows the HPS to master transactions to the slaves in the FPGA fabric.
- Lightweight HPS-to-FPGA AXI bridge—a lower performance 32-bit width bus that allows the HPS to master transactions to the slaves in the FPGA fabric.

The HPS–FPGA AXI bridges also allow the FPGA fabric to access the memory shared by one or both microprocessors, and provide asynchronous clock crossing with the clock from the FPGA fabric.

## HPS SDRAM Controller Subsystem

The HPS SDRAM controller subsystem contains a multiport SDRAM memory controller and DDR PHY that are shared between the FPGA fabric (through the FPGA-to-HPS SDRAM interface), the level 2 (L2) cache, and the level 3 (L3) system interconnect. The FPGA-to-HPS SDRAM interface supports AMBA AXI and Avalon<sup>®</sup> Memory-Mapped (Avalon-MM) interface standards, and provides up to four ports with separate read and write directions.

To maximize memory performance, the SDRAM controller subsystem supports command and data reordering, deficit round-robin arbitration with aging, and high-priority bypass features. The SDRAM controller subsystem supports DDR2, DDR3, LPDDR, or LPDDR2 devices up to 4 Gb in density and runs up to 400 MHz (800 Mbps data rate).

For easy migration, the FPGA-to-HPS SDRAM interface is compatible with the interface of the soft SDRAM memory controller IPs and hard SDRAM memory controllers in the FPGA fabric.

## FPGA Configuration and Processor Booting

The FPGA fabric and HPS in the SoC FPGA are powered independently. You can reduce the clock frequencies or gate the clocks to reduce dynamic power, or shut down the entire FPGA fabric to reduce total system power.

You can configure the FPGA fabric and boot the HPS independently, in any order, providing you with more design flexibility:

- You can boot the HPS before you power up and configure the FPGA fabric. After the system is running, the HPS reconfigures the FPGA fabric at any time under program control or through the FPGA configuration controller.
- You can power up both the HPS and the FPGA fabric together, configure the FPGA fabric first, and then upload the boot code to the HPS from the FPGA fabric.

## Hardware and Software Development

For hardware development, you can configure the HPS and connect your soft logic in the FPGA fabric to the HPS interfaces using the Qsys system integration tool in the Quartus II software.

For software development, the ARM-based SoC FPGA devices inherit the rich software development ecosystem available for the ARM Cortex-A9 MPCore processor. The software development process for Altera SoC FPGAs follows the same steps as those for other SoC devices. Altera also provides support for the Linux and VxWorks® operating systems.

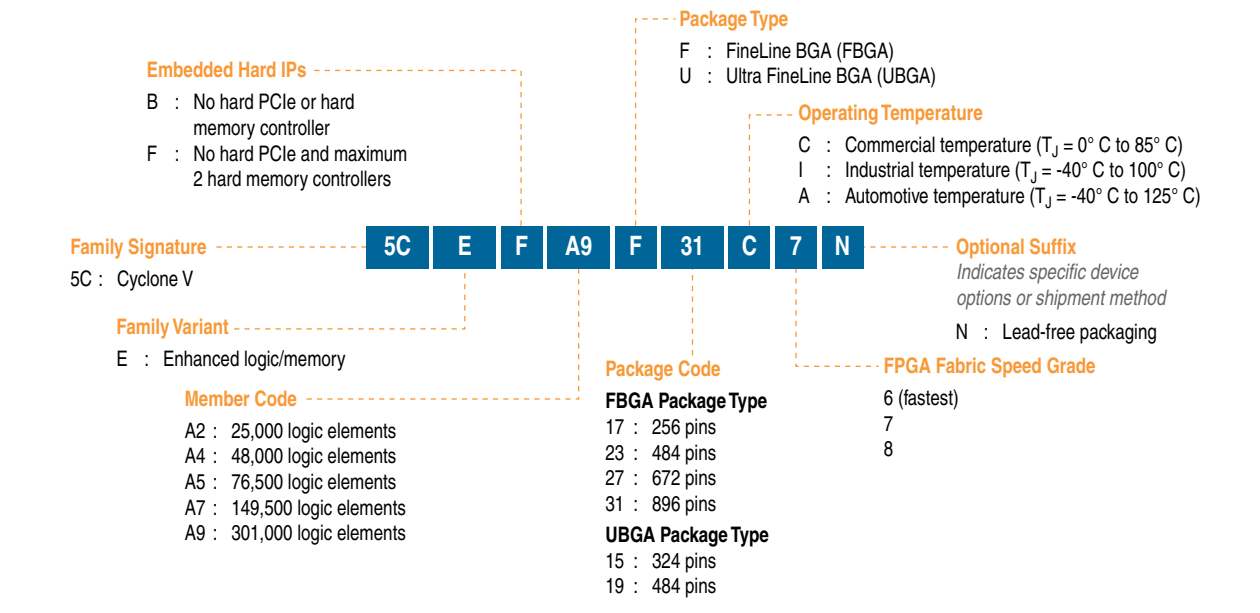
You can begin device-specific firmware and software development on the Altera SoC FPGA Virtual Target. The Virtual Target is a fast PC-based functional simulation of a target development system—a model of a complete development board that runs on a PC. The Virtual Target enables the development of device-specific production software that can run unmodified on actual hardware.



## Ordering Information

Figure 1-5 and Figure 1-6 show sample ordering codes and list the options available for Cyclone V E, GX, and GT devices.

**Figure 1-5. Ordering Information for Cyclone V E Devices—Preliminary**



**Figure 1-6. Ordering Information for Cyclone V GX and GT Devices—Preliminary**

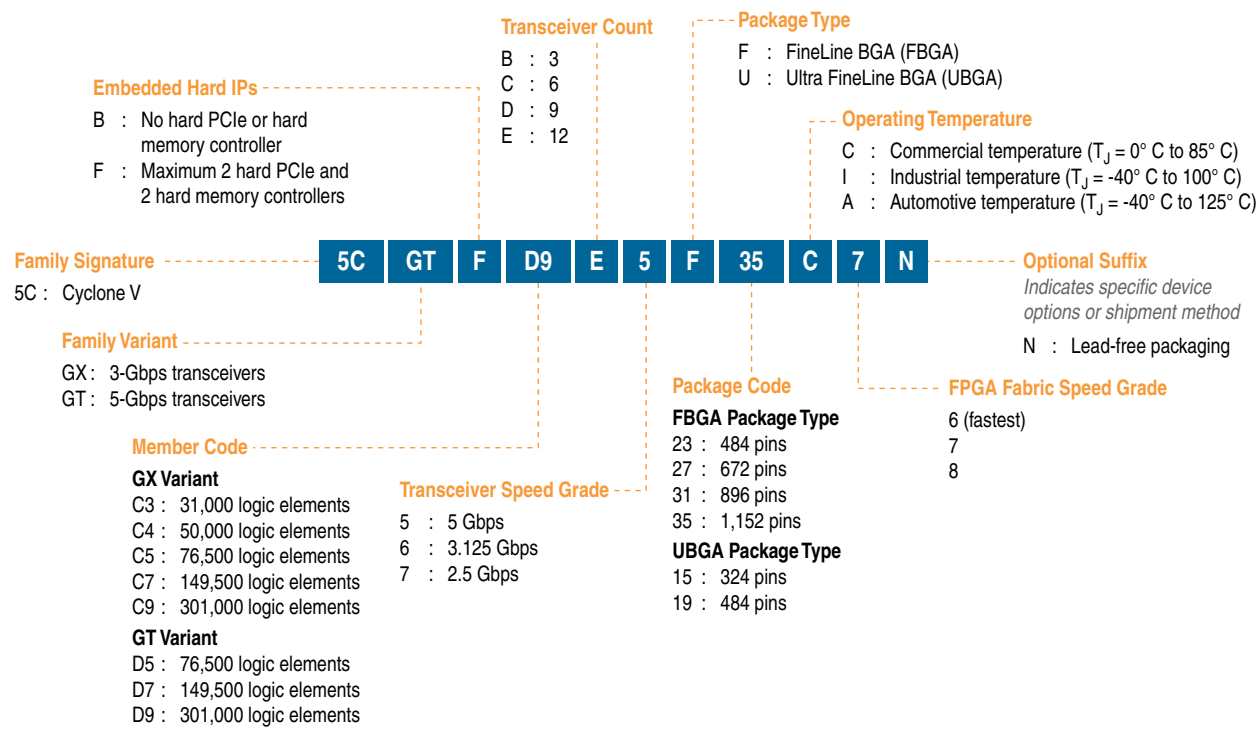
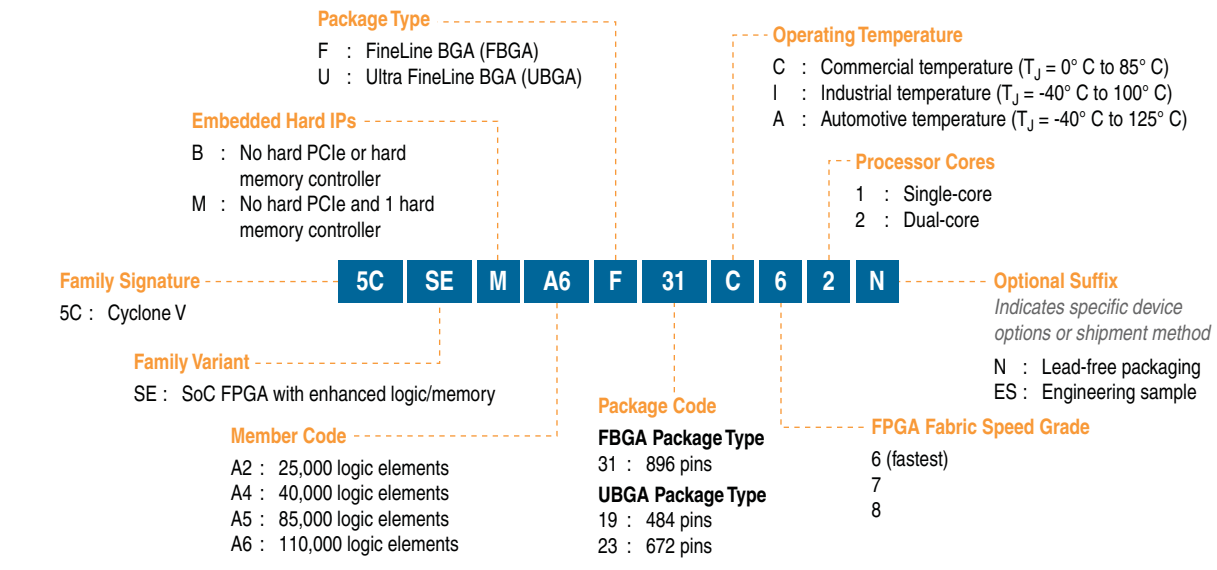
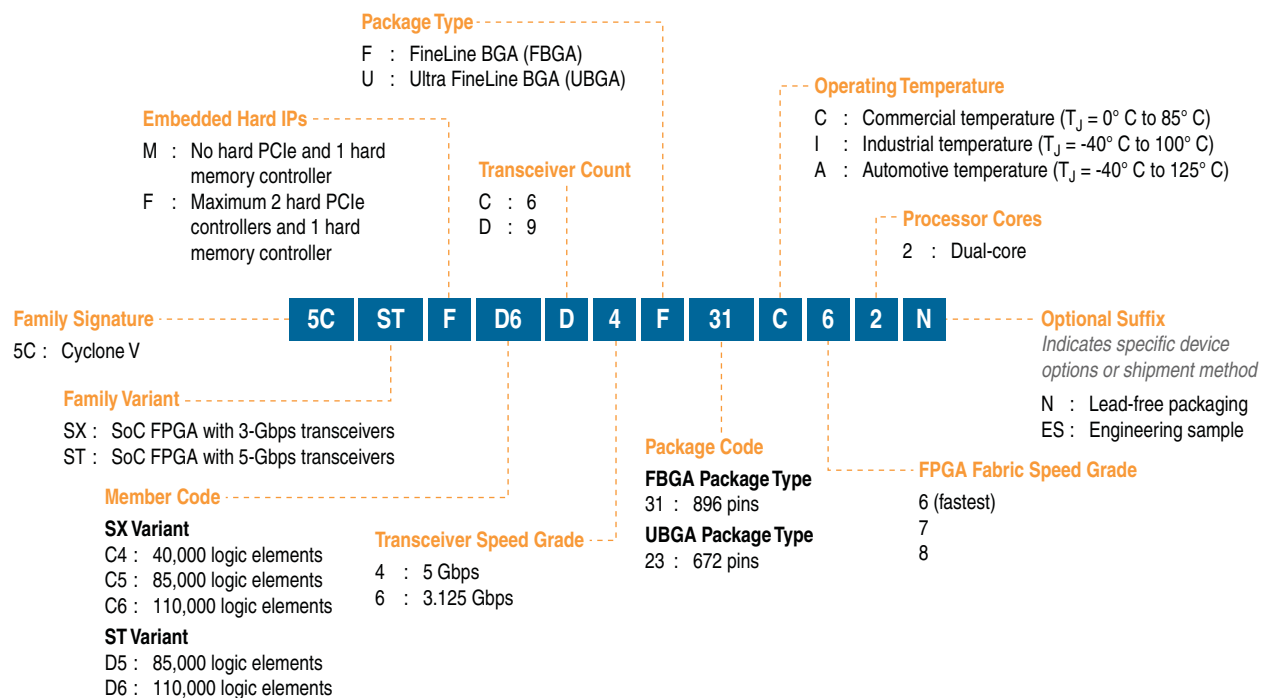


Figure 1-7 and Figure 1-8 show sample ordering codes and list the options available for Cyclone V SE, SX, and ST Devices.

**Figure 1-7. Ordering Information for Cyclone V SE Devices—Preliminary**



**Figure 1-8. Ordering Information for Cyclone V SX and ST Devices—Preliminary**



## Document Revision History

Table 1-15 lists the revision history for this document.

**Table 1-15. Document Revision History**

Date	Version	Changes
February 2012	1.2	<ul style="list-style-type: none"> <li>■ Updated Table 1-2, Table 1-3, and Table 1-6.</li> <li>■ Updated “Cyclone V Family Plan” on page 1-4 and “Clock Networks and PLL Clock Sources” on page 1-15.</li> <li>■ Updated Figure 1-1 and Figure 1-6.</li> </ul>
November 2011	1.1	<ul style="list-style-type: none"> <li>■ Updated Table 1-1, Table 1-2, Table 1-3, Table 1-4, Table 1-5, and Table 1-6.</li> <li>■ Updated Figure 1-4, Figure 1-5, Figure 1-6, Figure 1-7, and Figure 1-8.</li> <li>■ Updated “System Peripherals” on page 1-18, “HPS-FPGA AXI Bridges” on page 1-19, “HPS SDRAM Controller Subsystem” on page 1-19, “FPGA Configuration and Processor Booting” on page 1-19, and “Hardware and Software Development” on page 1-20.</li> <li>■ Minor text edits.</li> </ul>
October 2011	1.0	Initial release.



This chapter describes the electrical characteristics, switching characteristics, and configuration specifications for Cyclone® V devices. Electrical characteristics include operating conditions and power consumption. Switching characteristics list the transceiver specifications, and core and periphery performance. Configuration specifications cover power-on reset (POR) specifications, various configuration mode timing parameters, remote system upgrades timing, and user watchdog internal oscillator frequency specification. This chapter also describes I/O timing, including programmable I/O element (IOE) delay and programmable output buffer delay.

 For more information about the densities and packages of devices in the Cyclone V family, refer to the *Overview for Cyclone V Device Family* chapter.

## Electrical Characteristics

The following sections describe the electrical characteristics of Cyclone V devices.

### Operating Conditions

Cyclone V devices are rated according to a set of defined parameters. To maintain the highest possible performance and reliability of the Cyclone V devices, you must consider the operating requirements described in this chapter.

Cyclone V devices are offered in commercial and industrial grades. Commercial devices are offered in -6 (fastest), -7, and -8 speed grades. Industrial and automotive devices are offered in the -7 speed grade.

### Absolute Maximum Ratings

Absolute maximum ratings define the maximum operating conditions for Cyclone V devices. The values are based on experiments conducted with the devices and theoretical modeling of breakdown and damage mechanisms. The functional operation of the device is not implied for these conditions.



Conditions other than those listed in [Table 2-1](#) may cause permanent damage to the device. Additionally, device operation at the absolute maximum ratings for extended periods of time may have adverse effects on the device.

Table 2-1 lists the Cyclone V absolute maximum ratings.

**Table 2-1. Absolute Maximum Ratings for Cyclone V Devices—Preliminary**

Symbol	Description	Minimum	Maximum	Unit
$V_{CC}$	Core voltage and periphery circuitry power supply	-0.5	1.35	V
$V_{CCPGM}$	Configuration pins power supply	-0.5	3.75	V
$V_{CC\_AUX}$	Auxiliary supply	-0.5	3.75	V
$V_{CCBAT}$	Battery back-up power supply for design security volatile key register	-0.5	3.75	V
$V_{CCPD}$	I/O pre-driver power supply	-0.5	3.75	V
$V_{CCIO}$	I/O power supply	-0.5	3.9	V
$V_{CCA\_FPLL}$	PLL analog power supply	-0.5	3.75	V
$V_{CCH\_GXB}$	Transceiver high voltage power	-0.5	3.75	V
$V_{CCE\_GXB}$	Transceiver power	-0.5	1.21	V
$V_{CCL\_GXB}$	Clock network power	-0.5	1.21	V
$V_I$	DC input voltage	-0.5	4	V
$I_{OUT}$	DC output current per pin	-25	40	mA
$T_J$	Operating junction temperature	-55	125	°C
$T_{STG}$	Storage temperature (No bias)	-65	150	°C

#### Maximum Allowed Overshoot and Undershoot Voltage

During transitions, input signals may overshoot to the voltage listed in Table 2-2 and undershoot to -2.0 V for input currents less than 100 mA and periods shorter than 20 ns.

Table 2-2 lists the maximum allowed input overshoot voltage and the duration of the overshoot voltage as a percentage of device lifetime. The maximum allowed overshoot duration is specified as a percentage of high time over the lifetime of the device. A DC signal is equivalent to 100% duty cycle. For example, a signal that overshoots to 3.95 V can only be at 3.95 V for ~5% over the lifetime of the device; for a device lifetime of 10 years, this amounts to half a year.

**Table 2-2. Maximum Allowed Overshoot During Transitions for Cyclone V Devices—Preliminary**

Symbol	Description	Condition (V)	Overshoot Duration as % of High Time	Unit
$V_i$ (AC)	AC input voltage	3.7	100	%
		3.75	59.79	%
		3.8	33.08	%
		3.85	18.45	%
		3.9	10.36	%
		3.95	5.87	%
		4	3.34	%
		4.05	1.92	%
		4.1	1.11	%

## Recommended Operating Conditions

Recommended operating conditions are the functional operation limits for the AC and DC parameters for Cyclone V devices.

Table 2-3 lists the steady-state voltage values expected from Cyclone V devices. Power supply ramps must all be strictly monotonic, without plateaus.

**Table 2-3. Recommended Operating Conditions for Cyclone V Devices—Preliminary**

Symbol	Description	Condition	Minimum	Typical	Maximum	Unit
$V_{CC}$	Core voltage, periphery circuitry power supply, transceiver physical coding sublayer (PCS) power supply, and transceiver PCI Express® (PCIe®) hard IP digital power supply	—	1.07	1.1	1.13	V
$V_{CC\_AUX}$	Auxiliary supply	—	2.375	2.5	2.625	V
$V_{CCPD}$	I/O pre-driver (3.3 V) power supply	—	3.135	3.3	3.465	V
	I/O pre-driver (3.0 V) power supply	—	2.85	3.0	3.15	V
	I/O pre-driver (2.5 V) power supply	—	2.375	2.5	2.625	V
$V_{CCIO}$	I/O buffers (3.3 V) power supply	—	3.135	3.3	3.465	V
	I/O buffers (3.0 V) power supply	—	2.85	3.0	3.15	V
	I/O buffers (2.5 V) power supply	—	2.375	2.5	2.625	V
	I/O buffers (1.8 V) power supply	—	1.71	1.8	1.89	V
	I/O buffers (1.5 V) power supply	—	1.425	1.5	1.575	V
	I/O buffers (1.35 V) power supply	—	1.283	1.35	1.418	V
	I/O buffers (1.25 V) power supply	—	1.19	1.25	1.31	V
$V_{CCPGM}$	I/O buffers (1.2 V) power supply	—	1.14	1.2	1.26	V
	Configuration pins (3.3 V) power supply	—	3.135	3.3	3.465	V
	Configuration pins (3.0 V) power supply	—	2.85	3.0	3.15	V
	Configuration pins (2.5 V) power supply	—	2.375	2.5	2.625	V
$V_{CCBAT}^{(2)}$	Configuration pins (1.8 V) power supply	—	1.71	1.8	1.89	V
	Configuration pins (1.25 V) power supply	—	1.19	1.25	1.31	V
$V_{CCA\_FPLL}^{(1)}$	PLL analog voltage regulator power supply	—	2.375	2.5	2.625	V
$V_{CCBAT}^{(2)}$	Battery back-up power supply (For design security volatile key register)	—	1.2	—	3.0	V
$V_I$	DC input voltage	—	-0.5	—	3.6	V
$V_O$	Output voltage	—	0	—	$V_{CCIO}$	V
$T_J$	Operating junction temperature	Commercial	0	—	85	°C
		Industrial	-40	—	100	°C
		Automotive	-40	—	125	°C

**Table 2-3. Recommended Operating Conditions for Cyclone V Devices—Preliminary**

Symbol	Description	Condition	Minimum	Typical	Maximum	Unit
$t_{\text{RAMP}}$	Power supply ramp time	Standard POR (PORSEL=0)	200 $\mu\text{s}$	—	100 ms	—
		Fast POR (PORSEL=1)	200 $\mu\text{s}$	—	4 ms	—

**Notes to Table 2-3:**

- (1) PLL digital voltage is regulated from  $V_{\text{CCA\_FPLL}}$ .
- (2) If you do not use the design security feature in Cyclone V devices, connect  $V_{\text{CCBAT}}$  to a 1.5-V, 2.5-V, or 3.0-V power supply. The power-on reset (POR) circuitry monitors  $V_{\text{CCBAT}}$ . Cyclone V devices do not exit POR if  $V_{\text{CCBAT}}$  stays low.

Table 2-4 lists the transceiver power supply recommended operating conditions for Cyclone V GX devices.

**Table 2-4. Transceiver Power Supply Operating Conditions for Cyclone V GX Devices—Preliminary**

Symbol	Description	Minimum	Typical	Maximum	Unit
$V_{\text{CCH\_GXBL}}$	Transceiver high voltage power (left side)	2.375	2.5	2.625	V
$V_{\text{CCE\_GXBL}}$	Transmitter and receiver power (left side)	1.07	1.1	1.13	V
$V_{\text{CCL\_GXBL}}$	Clock network power (left side)	1.07	1.1	1.13	V

Table 2-5 lists the steady-state voltage values expected from Cyclone V system-on-a-chip (SoC) FPGA with ARM<sup>®</sup>-based hard processor system (HPS). Power supply ramps must all be strictly monotonic, without plateaus.

**Table 2-5. HPS Power Supply Operating Conditions for Cyclone V SE, SX, and ST Devices—Preliminary**

Symbol	Description	Minimum	Typical	Maximum	Unit
$V_{\text{CC\_HPS}}$	HPS core voltage and periphery circuitry power supply	1.07	1.1	1.13	V
$V_{\text{CCPD\_HPS}}$	HPS I/O pre-driver (3.3 V) power supply	3.135	3.3	3.465	V
	HPS I/O pre-driver (3.0 V) power supply	2.85	3.0	3.15	V
	HPS I/O pre-driver (2.5 V) power supply	2.375	2.5	2.625	V
$V_{\text{CCIO\_HPS}}$	HPS I/O buffers (3.3 V) power supply	3.135	3.3	3.465	V
	HPS I/O buffers (3.0 V) power supply	2.85	3.0	3.15	V
	HPS I/O buffers (2.5 V) power supply	2.375	2.5	2.625	V
	HPS I/O buffers (1.8 V) power supply	1.71	1.8	1.89	V
	HPS I/O buffers (1.5 V) power supply	1.425	1.5	1.575	V
	HPS I/O buffers (1.2 V) power supply	1.14	1.2	1.26	V
$V_{\text{CCRSTCLK\_HPS}}$	HPS reset and clock input pins (3.3 V) power supply	3.135	3.3	3.465	V
	HPS reset and clock input pins (3.0 V) power supply	2.85	3.0	3.15	V
	HPS reset and clock input pins (2.5 V) power supply	2.375	2.5	2.625	V
	HPS reset and clock input pins (1.8 V) power supply	1.71	1.8	1.89	V
$V_{\text{CCPLL\_HPS}}$	HPS PLL analog voltage regulator power supply	2.375	2.5	2.625	V




## DC Characteristics

This section lists the supply current, I/O pin leakage current, input pin capacitance, on-chip termination tolerance, and hot socketing specifications.

### Supply Current

Standby current is the current drawn from the respective power rails used for power budgeting. Use the Excel-based Early Power Estimator (EPE) to estimate supply current for your design because these currents vary greatly with the resources you use.

 For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in the *Quartus II Handbook*.

### I/O Pin Leakage Current

Table 2-6 lists the Cyclone V I/O pin leakage current specifications.

**Table 2-6. I/O Pin Leakage Current for Cyclone V Devices—Preliminary**

Symbol	Description	Conditions	Min	Typ	Max	Unit
$I_I$	Input pin	$V_I = 0\text{ V to }V_{CCIO\text{MAX}}$	-30	—	30	$\mu\text{A}$
$I_{OZ}$	Tri-stated I/O pin	$V_O = 0\text{ V to }V_{CCIO\text{MAX}}$	-30	—	30	$\mu\text{A}$

### Bus Hold Specifications

Table 2-7 lists the Cyclone V device bus hold specifications.

**Table 2-7. Bus Hold Parameters for Cyclone V Devices—Preliminary (Part 1 of 2) <sup>(1)</sup>**

Parameter	Symbol	Conditions	$V_{CCIO}\text{ (V)}$												Unit
			1.2		1.5		1.8		2.5		3.0		3.3		
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Bus-hold, low, sustaining current	$I_{SUSL}$	$V_{IN} > V_{IL}$ (max.)	8	—	12	—	30	—	50	—	70	—	70	—	$\mu\text{A}$
Bus-hold, high, sustaining current	$I_{SUSH}$	$V_{IN} < V_{IH}$ (min.)	-8	—	-12	—	-30	—	-50	—	-70	—	-70	—	$\mu\text{A}$
Bus-hold, low, overdrive current	$I_{ODL}$	$0\text{V} < V_{IN} < V_{CCIO}$	—	125	—	175	—	200	—	300	—	500	—	500	$\mu\text{A}$
Bus-hold, high, overdrive current	$I_{ODH}$	$0\text{V} < V_{IN} < V_{CCIO}$	—	-125	—	-175	—	-200	—	-300	—	-500	—	-500	$\mu\text{A}$

**Table 2-7. Bus Hold Parameters for Cyclone V Devices—Preliminary (Part 2 of 2) <sup>(1)</sup>**

Parameter	Symbol	Conditions	$V_{CCIO}$ (V)												Unit
			1.2		1.5		1.8		2.5		3.0		3.3		
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Bus-hold trip point	$V_{TRIP}$	—	0.3	0.9	0.375	1.125	0.68	1.07	0.7	1.7	0.8	2	0.8	2	V

**Note to Table 2-7:**

(1) The bus-hold trip points are based on calculated input voltages from the JEDEC standard.

**On-Chip Termination (OCT) Specifications**

If you enable OCT calibration, calibration is automatically performed at power up for I/O pins connected to the calibration block. Calibration accuracy for the calibrated on-chip series termination ( $R_S$  OCT) and on-chip parallel termination ( $R_T$  OCT) are applicable at the moment of calibration. When process, voltage, and temperature (PVT) conditions change after calibration, the tolerance may change.

Table 2–8 lists the Cyclone V OCT termination calibration accuracy specifications.

**Table 2–8. OCT Calibration Accuracy Specifications for Cyclone V Devices—Preliminary (1)**

Symbol	Description	Conditions (V)	Calibration Accuracy			Unit
			C6 Speed Grade	C7, I7 Speed Grade	C8, A7 Speed Grade	
25-Ω R <sub>S</sub>	Internal series termination with calibration (25-Ω setting)	V <sub>CCIO</sub> = 3.0, 2.5, 1.8, 1.5, 1.2	±15	±15	±15	%
50-Ω R <sub>S</sub>	Internal series termination with calibration (50-Ω setting)	V <sub>CCIO</sub> = 3.0, 2.5, 1.8, 1.5, 1.2	±15	±15	±15	%
34-Ω and 40-Ω R <sub>S</sub>	Internal series termination with calibration (34-Ω and 40-Ω setting)	V <sub>CCIO</sub> = 1.5, 1.35, 1.25, 1.2	±15	±15	±15	%
48-Ω, 60-Ω, and 80-Ω R <sub>S</sub>	Internal series termination with calibration (48-Ω, 60-Ω, and 80-Ω setting)	V <sub>CCIO</sub> = 1.2	±15	±15	±15	%
50-Ω R <sub>T</sub>	Internal parallel termination with calibration (50-Ω setting)	V <sub>CCIO</sub> = 2.5, 1.8, 1.5, 1.2	-10 to +40	-10 to +40	-10 to +40	%
20-Ω, 30-Ω, 40-Ω, 60-Ω, and 120-Ω R <sub>T</sub>	Internal parallel termination with calibration (20-Ω, 30-Ω, 40-Ω, 60-Ω, and 120-Ω setting)	V <sub>CCIO</sub> = 1.5, 1.35, 1.25	-10 to +40	-10 to +40	-10 to +40	%
60-Ω and 120-Ω R <sub>T</sub>	Internal parallel termination with calibration (60-Ω and 120-Ω setting)	V <sub>CCIO</sub> = 1.2	-10 to +40	-10 to +40	-10 to +40	%
25-Ω R <sub>S_left_shift</sub>	Internal left shift series termination with calibration (25-Ω R <sub>S_left_shift</sub> setting)	V <sub>CCIO</sub> = 3.0, 2.5, 1.8, 1.5, 1.2	±15	±15	±15	%

**Note to Table 2–8:**

(1) OCT calibration accuracy is valid at the time of calibration only.

Table 2-9 lists the Cyclone V OCT without calibration resistance tolerance to PVT changes.

**Table 2-9. OCT Without Calibration Resistance Tolerance Specifications for Cyclone V Devices—Preliminary**

Symbol	Description	Conditions (V)	Resistance Tolerance			Unit
			C6 Speed Grade	C7, I7 Speed Grade	C8, A7 Speed Grade	
25-Ω R <sub>S</sub>	Internal series termination without calibration (25-Ω setting)	V <sub>CCIO</sub> = 3.0 and 2.5	±30	±40	±40	%
25-Ω R <sub>S</sub>	Internal series termination without calibration (25-Ω setting)	V <sub>CCIO</sub> = 1.8 and 1.5	±30	±40	±40	%
25-Ω R <sub>S</sub>	Internal series termination without calibration (25-Ω setting)	V <sub>CCIO</sub> = 1.2	±35	±50	±50	%
50-Ω R <sub>S</sub>	Internal series termination without calibration (50-Ω setting)	V <sub>CCIO</sub> = 3.0 and 2.5	±30	±40	±40	%
50-Ω R <sub>S</sub>	Internal series termination without calibration (50-Ω setting)	V <sub>CCIO</sub> = 1.8 and 1.5	±30	±40	±40	%
50-Ω R <sub>S</sub>	Internal series termination without calibration (50-Ω setting)	V <sub>CCIO</sub> = 1.2	±35	±50	±50	%
100-Ω R <sub>D</sub>	Internal differential termination (100-Ω setting)	V <sub>CCIO</sub> = 2.5	±25	TBD	TBD	%

OCT calibration is automatically performed at power up for the OCT-enabled I/O pins. Table 2-10 lists OCT variation with temperature and voltage after power-up calibration. Use Table 2-10 to determine the OCT variation after power-up calibration and Equation 2-1 to determine the OCT variation without recalibration.

**Equation 2-1. OCT Variation Without Recalibration—Preliminary (1), (2), (3), (4), (5), (6)**

$$R_{OCT} = R_{SCAL} \left( 1 + \left\langle \frac{dR}{dT} \times \Delta T \right\rangle \pm \left\langle \frac{dR}{dV} \times \Delta V \right\rangle \right)$$

**Notes to Equation 2-1:**

- (1) The R<sub>OCT</sub> value calculated from Equation 2-1 shows the range of OCT resistance with the variation of temperature and V<sub>CCIO</sub>.
- (2) R<sub>SCAL</sub> is the OCT resistance value at power-up.
- (3) ΔT is the variation of temperature with respect to the temperature at power up.
- (4) ΔV is the variation of voltage with respect to V<sub>CCIO</sub> at power up.
- (5) dR/dT is the percentage change of R<sub>SCAL</sub> with temperature.
- (6) dR/dV is the percentage change of R<sub>SCAL</sub> with voltage.

Table 2-10 lists the OCT variation after the power-up calibration.

**Table 2-10. OCT Variation after Power-Up Calibration for Cyclone V Devices—Preliminary <sup>(1)</sup>**

Symbol	Description	V <sub>CCIO</sub> (V)	Typical	Unit
dR/dV	OCT variation with voltage without recalibration	3.0	0.0297	% / mV
		2.5	0.0344	
		1.8	0.0499	
		1.5	0.0744	
		1.2	0.1241	
dR/dT	OCT variation with temperature without recalibration	3.0	0.189	% / °C
		2.5	0.208	
		1.8	0.266	
		1.5	0.273	
		1.2	0.317	

**Note to Table 2-10:**

(1) Valid for a V<sub>CCIO</sub> range of ±5% and a temperature range of 0° to 85°C.

### Pin Capacitance

Table 2-11 lists the Cyclone V device family pin capacitance.

**Table 2-11. Pin Capacitance for Cyclone V Devices**

Symbol	Description	Value	Unit
C <sub>IOTB</sub>	Input capacitance on top and bottom I/O pins	5.5	pF
C <sub>IOLR</sub>	Input capacitance on left and right I/O pins	5.5	pF
C <sub>OUTFB</sub>	Input capacitance on dual-purpose clock output and feedback pins	5.5	pF

### Hot Socketing

Table 2-12 lists the hot socketing specifications for Cyclone V devices.

**Table 2-12. Hot Socketing Specifications for Cyclone V Devices—Preliminary**

Symbol	Description	Maximum
I <sub>IOPIN (DC)</sub>	DC current per I/O pin	300 μA
I <sub>IOPIN (AC)</sub>	AC current per I/O pin	8 mA <sup>(1)</sup>
I <sub>XCVR-TX (DC)</sub>	DC current per transceiver transmitter (TX) pin	100 mA
I <sub>XCVR-RX (DC)</sub>	DC current per transceiver receiver (RX) pin	50 mA

**Note to Table 2-12:**

(1) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns, |I<sub>IOPIN</sub>| = C dv/dt, in which C is the I/O pin capacitance and dv/dt is the slew rate.

## Internal Weak Pull-Up Resistor

Table 2-13 lists the weak pull-up resistor values for Cyclone V devices.

**Table 2-13. Internal Weak Pull-Up Resistor Values for Cyclone V Devices—Preliminary (1), (2)**

Symbol	Description	Conditions (V) (3)	Typ (4)	Unit
R <sub>PU</sub>	Value of the I/O pin pull-up resistor before and during configuration, as well as user mode if you have enabled the programmable pull-up resistor option.	V <sub>CCIO</sub> = 3.3 ±5%	25	kΩ
		V <sub>CCIO</sub> = 3.0 ±5%	25	kΩ
		V <sub>CCIO</sub> = 2.5 ±5%	25	kΩ
		V <sub>CCIO</sub> = 1.8 ±5%	25	kΩ
		V <sub>CCIO</sub> = 1.5 ±5%	25	kΩ
		V <sub>CCIO</sub> = 1.35 ±5%	25	kΩ
		V <sub>CCIO</sub> = 1.25 ±5%	25	kΩ
		V <sub>CCIO</sub> = 1.2 ±5%	25	kΩ

### Notes to Table 2-13:

- (1) All I/O pins have an option to enable weak pull-up except the configuration, test, and JTAG pins.
- (2) The internal weak pull-down feature is only available for the JTAG  $\overline{\text{TRCK}}$  pin. The typical value for this internal weak pull-down resistor is approximately 25 kΩ.
- (3) Pin pull-up resistance values may be lower if an external source drives the pin higher than V<sub>CCIO</sub>.
- (4) These specifications are valid with ±10% tolerances to cover changes over PVT.

## I/O Standard Specifications

Table 2-14 through Table 2-19 list the input voltage (V<sub>IH</sub> and V<sub>IL</sub>), output voltage (V<sub>OH</sub> and V<sub>OL</sub>), and current drive characteristics (I<sub>OH</sub> and I<sub>OL</sub>) for various I/O standards supported by Cyclone V devices. These tables also list the Cyclone V device family I/O standard specifications. The V<sub>OL</sub> and V<sub>OH</sub> values are valid at the corresponding I<sub>OH</sub> and I<sub>OL</sub>, respectively.

For an explanation of terms used in Table 2-14 through Table 2-19, refer to “Glossary” on page 2-37.

**Table 2-14. Single-Ended I/O Standards for Cyclone V Devices—Preliminary (Part 1 of 2)**

I/O Standard	V <sub>CCIO</sub> (V)			V <sub>IL</sub> (V)		V <sub>IH</sub> (V)		V <sub>OL</sub> (V)	V <sub>OH</sub> (V)	I <sub>OL</sub> (mA)	I <sub>OH</sub> (mA)
	Min	Typ	Max	Min	Max	Min	Max	Max	Min		
3.3-V LVTTTL	3.135	3.3	3.465	-0.3	0.8	1.7	3.6	0.45	2.4	4	-4
3.3-V LVCMOS	3.135	3.3	3.465	-0.3	0.8	1.7	3.6	0.2	V <sub>CCIO</sub> - 0.2	2	-2
3.0-V LVTTTL	2.85	3	3.15	-0.3	0.8	1.7	3.6	0.4	2.4	2	-2
3.0-V LVCMOS	2.85	3	3.15	-0.3	0.8	1.7	3.6	0.2	V <sub>CCIO</sub> - 0.2	0.1	-0.1
3.0-V PCI	2.85	3	3.15	—	0.3 × V <sub>CCIO</sub>	0.5 × V <sub>CCIO</sub>	V <sub>CCIO</sub> + 0.3	0.1 × V <sub>CCIO</sub>	0.9 × V <sub>CCIO</sub>	1.5	-0.5
3.0-V PCI-X	2.85	3	3.15	—	0.35 × V <sub>CCIO</sub>	0.5 × V <sub>CCIO</sub>	V <sub>CCIO</sub> + 0.3	0.1 × V <sub>CCIO</sub>	0.9 × V <sub>CCIO</sub>	1.5	-0.5
2.5 V	2.375	2.5	2.625	-0.3	0.7	1.7	3.6	0.4	2	1	-1
1.8 V	1.71	1.8	1.89	-0.3	0.35 × V <sub>CCIO</sub>	0.65 × V <sub>CCIO</sub>	V <sub>CCIO</sub> + 0.3	0.45	V <sub>CCIO</sub> - 0.45	2	-2

**Table 2-14. Single-Ended I/O Standards for Cyclone V Devices—Preliminary (Part 2 of 2)**

I/O Standard	V <sub>CCIO</sub> (V)			V <sub>IL</sub> (V)		V <sub>IH</sub> (V)		V <sub>OL</sub> (V)	V <sub>OH</sub> (V)	I <sub>OL</sub> (mA)	I <sub>OH</sub> (mA)
	Min	Typ	Max	Min	Max	Min	Max	Max	Min		
1.5 V	1.425	1.5	1.575	-0.3	0.35 × V <sub>CCIO</sub>	0.65 × V <sub>CCIO</sub>	V <sub>CCIO</sub> + 0.3	0.25 × V <sub>CCIO</sub>	0.75 × V <sub>CCIO</sub>	2	-2
1.2 V	1.14	1.2	1.26	-0.3	0.35 × V <sub>CCIO</sub>	0.65 × V <sub>CCIO</sub>	V <sub>CCIO</sub> + 0.3	0.25 × V <sub>CCIO</sub>	0.75 × V <sub>CCIO</sub>	2	-2

**Table 2-15. Single-Ended SSTL and HSTL I/O Reference Voltage Specifications for Cyclone V Devices—Preliminary**

I/O Standard	V <sub>CCIO</sub> (V)			V <sub>REF</sub> (V)			V <sub>TT</sub> (V)		
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max
SSTL-2 Class I, II	2.375	2.5	2.625	0.49 × V <sub>CCIO</sub>	0.5 × V <sub>CCIO</sub>	0.51 × V <sub>CCIO</sub>	V <sub>REF</sub> - 0.04	V <sub>REF</sub>	V <sub>REF</sub> + 0.04
SSTL-18 Class I, II	1.71	1.8	1.89	0.833	0.9	0.969	V <sub>REF</sub> - 0.04	V <sub>REF</sub>	V <sub>REF</sub> + 0.04
SSTL-15 Class I, II	1.425	1.5	1.575	0.49 × V <sub>CCIO</sub>	0.5 × V <sub>CCIO</sub>	0.51 × V <sub>CCIO</sub>	0.49 × V <sub>CCIO</sub>	0.5 × V <sub>CCIO</sub>	0.51 × V <sub>CCIO</sub>
SSTL 135 Class I, II	1.283	1.35	1.418	0.49 × V <sub>CCIO</sub>	0.5 × V <sub>CCIO</sub>	0.51 × V <sub>CCIO</sub>	0.49 × V <sub>CCIO</sub>	0.5 × V <sub>CCIO</sub>	0.51 × V <sub>CCIO</sub>
SSTL 125 Class I, II	1.19	1.25	1.26	0.49 × V <sub>CCIO</sub>	0.5 × V <sub>CCIO</sub>	0.51 × V <sub>CCIO</sub>	0.49 × V <sub>CCIO</sub>	0.5 × V <sub>CCIO</sub>	0.51 × V <sub>CCIO</sub>
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	—	V <sub>CCIO</sub> /2	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.68	0.75	0.9	—	V <sub>CCIO</sub> /2	—
HSTL-12 Class I, II	1.14	1.2	1.26	0.47 × V <sub>CCIO</sub>	0.5 × V <sub>CCIO</sub>	0.53 × V <sub>CCIO</sub>	—	V <sub>CCIO</sub> /2	—
HSUL-12	1.14	1.2	1.3	0.49 × V <sub>CCIO</sub>	0.5 × V <sub>CCIO</sub>	0.51 × V <sub>CCIO</sub>	—	—	—

**Table 2-16. Single-Ended SSTL and HSTL I/O Standards Signal Specifications for Cyclone V Devices—Preliminary (Part 1 of 2)**

I/O Standard	V <sub>IL(DC)</sub> (V)		V <sub>IH(DC)</sub> (V)		V <sub>IL(AC)</sub> (V)	V <sub>IH(AC)</sub> (V)	V <sub>OL</sub> (V)	V <sub>OH</sub> (V)	I <sub>ol</sub> (mA)	I <sub>oh</sub> (mA)
	Min	Max	Min	Max	Max	Min	Max	Min		
SSTL-2 Class I	-0.3	V <sub>REF</sub> - 0.15	V <sub>REF</sub> + 0.15	V <sub>CCIO</sub> + 0.3	V <sub>REF</sub> - 0.31	V <sub>REF</sub> + 0.31	V <sub>TT</sub> - 0.608	V <sub>TT</sub> + 0.608	8.1	-8.1
SSTL-2 Class II	-0.3	V <sub>REF</sub> - 0.15	V <sub>REF</sub> + 0.15	V <sub>CCIO</sub> + 0.3	V <sub>REF</sub> - 0.31	V <sub>REF</sub> + 0.31	V <sub>TT</sub> - 0.81	V <sub>TT</sub> + 0.81	16.2	-16.2
SSTL-18 Class I	-0.3	V <sub>REF</sub> - 0.125	V <sub>REF</sub> + 0.125	V <sub>CCIO</sub> + 0.3	V <sub>REF</sub> - 0.25	V <sub>REF</sub> + 0.25	V <sub>TT</sub> - 0.603	V <sub>TT</sub> + 0.603	6.7	-6.7
SSTL-18 Class II	-0.3	V <sub>REF</sub> - 0.125	V <sub>REF</sub> + 0.125	V <sub>CCIO</sub> + 0.3	V <sub>REF</sub> - 0.25	V <sub>REF</sub> + 0.25	0.28	V <sub>CCIO</sub> - 0.28	13.4	-13.4
SSTL-15 Class I	—	V <sub>REF</sub> - 0.1	V <sub>REF</sub> + 0.1	—	V <sub>REF</sub> - 0.175	V <sub>REF</sub> + 0.175	0.2 × V <sub>CCIO</sub>	0.8 × V <sub>CCIO</sub>	8	-8
SSTL-15 Class II	—	V <sub>REF</sub> - 0.1	V <sub>REF</sub> + 0.1	—	V <sub>REF</sub> - 0.175	V <sub>REF</sub> + 0.175	0.2 × V <sub>CCIO</sub>	0.8 × V <sub>CCIO</sub>	16	-16
SSTL 135	—	V <sub>REF</sub> - 0.09	V <sub>REF</sub> + 0.09	—	V <sub>REF</sub> - 0.16	V <sub>REF</sub> + 0.16	TBD <sup>(1)</sup>	TBD <sup>(1)</sup>	TBD <sup>(1)</sup>	TBD <sup>(1)</sup>

**Table 2-16. Single-Ended SSTL and HSTL I/O Standards Signal Specifications for Cyclone V Devices—Preliminary (Part 2 of 2)**

I/O Standard	$V_{IL(DC)}$ (V)		$V_{IH(DC)}$ (V)		$V_{IL(AC)}$ (V)	$V_{IH(AC)}$ (V)	$V_{OL}$ (V)	$V_{OH}$ (V)	$I_{ol}$ (mA)	$I_{oh}$ (mA)
	Min	Max	Min	Max	Max	Min	Max	Min		
SSTL 125	—	$V_{REF} - 0.85$	$V_{REF} + 0.85$	—	$V_{REF} - 0.15$	$V_{REF} + 0.15$	TBD (1)	TBD (1)	TBD (1)	TBD (1)
HSTL-18 Class I	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	8	-8
HSTL-18 Class II	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	16	-16
HSTL-15 Class I	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	8	-8
HSTL-15 Class II	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	16	-16
HSTL-12 Class I	-0.1 5	$V_{REF} - 0.08$	$V_{REF} + 0.08$	$V_{CCIO} + 0.15$	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$0.25 \times V_{CCIO}$	$0.75 \times V_{CCIO}$	8	-8
HSTL-12 Class II	-0.1 5	$V_{REF} - 0.08$	$V_{REF} + 0.08$	$V_{CCIO} + 0.15$	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$0.25 \times V_{CCIO}$	$0.75 \times V_{CCIO}$	16	-16
HSUL-12	—	$V_{REF} - 0.13$	$V_{REF} + 0.13$	—	$V_{REF} - 0.22$	$V_{REF} + 0.22$	$0.1 \times V_{CCIO}$	$0.9 \times V_{CCIO}$	TBD (1)	TBD (1)

Note to Table 2-16:

(1) Pending silicon characterization.

**Table 2-17. Differential SSTL I/O Standards for Cyclone V Devices—Preliminary**

I/O Standard	$V_{CCIO}$ (V)			$V_{SWING(DC)}$ (V)		$V_{X(AC)}$ (V)			$V_{SWING(AC)}$ (V)		$V_{OX(AC)}$ (V)		
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Max	Min	Typ	Max
SSTL-2 Class I, II	2.375	2.5	2.625	0.3	$V_{CCIO} + 0.6$	$V_{CCIO}/2 - 0.2$	—	$V_{CCIO}/2 + 0.2$	0.62	$V_{CCIO} + 0.6$	$V_{CCIO}/2 - 0.15$	—	$V_{CCIO}/2 + 0.15$
SSTL-18 Class I, II	1.71	1.8	1.89	0.25	$V_{CCIO} + 0.6$	$V_{CCIO}/2 - 0.175$	—	$V_{CCIO}/2 + 0.175$	0.5	$V_{CCIO} + 0.6$	$V_{CCIO}/2 - 0.125$	—	$V_{CCIO}/2 + 0.125$
SSTL-15 Class I, II	1.425	1.5	1.575	0.2	-0.2	-0.15	—	0.15	-0.35	0.35	—	$V_{CCIO}/2$	—
SSTL 135	1.283	1.35	1.45	0.2	-0.2	$V_{REF} - 0.135$	$V_{CCIO}/2$	$V_{REF} + 0.135$	TBD (1)	TBD (1)	$V_{REF} - 0.15$	—	$V_{REF} + 0.15$
SSTL 125	1.19	1.25	1.31	TBD (1)	—	TBD (1)	$V_{CCIO}/2$	TBD (1)	TBD (1)	—	TBD (1)	TBD (1)	TBD (1)

Note to Table 2-17:

(1) Pending silicon characterization.



**Table 2-18. Differential HSTL I/O Standards for Cyclone V Devices—Preliminary**

I/O Standard	V <sub>CCIO</sub> (V)			V <sub>DIF(DC)</sub> (V)		V <sub>X(AC)</sub> (V)			V <sub>CM(DC)</sub> (V)			V <sub>DIF(AC)</sub> (V)	
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Typ	Max	Min	Max
HSTL-18 Class I, II	1.71	1.8	1.89	0.2	—	0.78	—	1.12	0.78	—	1.12	0.4	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.2	—	0.68	—	0.9	0.68	—	0.9	0.4	—
HSTL-12 Class I, II	1.14	1.2	1.26	0.16	V <sub>CCIO</sub> + 0.3	—	0.5 x V <sub>CCIO</sub>	—	0.4 x V <sub>CCIO</sub>	0.5 x V <sub>CCIO</sub>	0.6 x V <sub>CCIO</sub>	0.3	V <sub>CCIO</sub> + 0.48
HSUL-12	1.14	1.2	1.3	0.26	0.26	0.5 x V <sub>CCIO</sub> - 0.12	0.5 x V <sub>CCIO</sub>	0.5 x V <sub>CCIO</sub> + 0.12	0.4 x V <sub>CCIO</sub>	0.5 x V <sub>CCIO</sub>	0.6 x V <sub>CCIO</sub>	0.44	0.44

**Table 2-19. Differential I/O Standard Specifications for Cyclone V Devices—Preliminary <sup>(1)</sup>**

I/O Standard	V <sub>CCIO</sub> (V)			V <sub>ID</sub> (mV)			V <sub>ICM(DC)</sub> (V)		V <sub>OD</sub> (V) <sup>(2)</sup>			V <sub>OCM</sub> (V) <sup>(2)</sup>		
	Min	Typ	Max	Min	Condition	Max	Min	Max	Min	Typ	Max	Min	Typ	Max
PCML	Transmitter, receiver, and input reference clock pins of high-speed transceivers use the PCML I/O standard. For transmitter, receiver, and reference clock I/O pin specifications, refer to <a href="#">Table 2-20 on page 2-14</a> .													
2.5 V LVDS	2.375	2.5	2.625	100	V <sub>CM</sub> = 1.25 V	—	0.05	1.8	0.247	—	0.6	1.125	1.25	1.375
RSDS (HIO)	2.375	2.5	2.625	100	V <sub>CM</sub> = 1.25 V	—	0.3	1.4	0.1	0.2	0.6	0.5	1.2	1.4
Mini-LVDS (HIO)	2.375	2.5	2.625	200	—	600	0.4	1.325	0.25	—	0.6	1	1.2	1.4
LVPECL	2.375	2.5	2.625	300	—	—	0.6	1.8	—	—	—	—	—	—
SLVS	2.375	2.5	2.625	100	V <sub>CM</sub> = 1.25 V	—	0.05	1.8	—	—	—	—	—	—

**Notes to Table 2-19:**

- (1) The 1.4-V and 1.5-V PCML transceiver I/O standard specifications are described in “[Transceiver Performance Specifications](#)” on page 2-14.
- (2) RL range: 90 ≤ RL ≤ 110 Ω

## Power Consumption

Altera offers two ways to estimate power consumption for a design—the Excel-based Early Power Estimator (EPE) and the Quartus® II PowerPlay Power Analyzer feature.



You typically use the interactive Excel-based EPE before designing the FPGA to get a magnitude estimate of the device power. The Quartus II PowerPlay Power Analyzer provides better quality estimates based on the specifics of the design after you complete place-and-route. The PowerPlay Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities that, when combined with detailed circuit models, yields very accurate power estimates.



For more information about power estimation tools, refer to the [PowerPlay Early Power Estimator User Guide](#) and the [PowerPlay Power Analysis](#) chapter in the [Quartus II Handbook](#).

## Switching Characteristics

This section provides performance characteristics of Cyclone V core and periphery blocks for commercial grade devices.

These characteristics can be designated as preliminary or final.

- Preliminary characteristics are obtained using simulation results, process data, and other known parameters. The title of these tables show the designation as “Preliminary.”
- Final numbers are based on actual silicon characterization and testing. The numbers reflect the actual performance of the device under worst-case silicon process, voltage, and junction temperature conditions. There are no designations on finalized tables.

## Transceiver Performance Specifications

This section describes transceiver performance specifications.

Table 2–20 lists the Cyclone V GX transceiver specifications.

**Table 2–20. Transceiver Specifications for Cyclone V GX Devices—Preliminary (Part 1 of 3)**

Symbol/ Description	Conditions	C6 Speed Grade			C7, I7 Speed Grade			C8, A7 Speed Grade			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
<b>Reference Clock</b>											
Supported I/O Standards	<b>1.2 V PCML, 1.5 V PCML, 2.5 V PCML, Differential LVPECL <sup>(1)</sup>, HCSL, and LVDS</b>										
Input frequency from REFCLK input pins	—	27	—	550	27	—	550	27	—	550	MHz
Duty cycle	—	45	—	55	45	—	55	45	—	55	%
Peak-to-peak differential input voltage	—	200	—	2000	200	—	2000	200	—	2000	mV
Spread-spectrum modulating clock frequency	PCIe	30	—	33	30	—	33	30	—	33	kHz
Spread-spectrum downspread	PCIe	—	0 to –0.5%	—	—	0 to –0.5%	—	—	0 to –0.5%	—	—
On-chip termination resistors	—	—	100	—	—	100	—	—	100	—	Ω
V <sub>ICM</sub> (AC coupled)	—	1.1 <sup>(2)</sup>			1.1 <sup>(2)</sup>			1.1 <sup>(2)</sup>			V
V <sub>ICM</sub> (DC coupled)	HCSL I/O standard for the PCIe reference clock	250	—	550	250	—	550	250	—	550	mV
R <sub>REF</sub>	—	—	2000 ±1%	—	—	2000 ±1%	—	—	2000 ±1%	—	Ω

**Table 2-20. Transceiver Specifications for Cyclone V GX Devices—Preliminary (Part 2 of 3)**

Symbol/ Description	Conditions	C6 Speed Grade			C7, I7 Speed Grade			C8, A7 Speed Grade			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
<b>Transceiver Clocks</b>											
fixedclk clock frequency	PCIe Receiver Detect	—	125	—	—	125	—	—	125	—	MHz
Avalon® Memory-Mapped (Avalon-MM) PHY management clock frequency	< 150										MHz
<b>Receiver</b>											
Supported I/O Standards	<b>1.5 V PCML, 2.5 V PCML, LVPECL, and LVDS</b>										
Data rate	—	614	—	3125	614	—	3125	614	—	2500	Mbps
Absolute V <sub>MAX</sub> for a receiver pin <sup>(3)</sup>	—	—	—	1.2	—	—	1.2	—	—	1.2	V
Absolute V <sub>MIN</sub> for a receiver pin	—	-0.4	—	—	-0.4	—	—	-0.4	—	—	V
Maximum peak-to-peak differential input voltage V <sub>ID</sub> (diff p-p) before device configuration	—	—	—	1.6	—	—	1.6	—	—	1.6	V
Maximum peak-to-peak differential input voltage V <sub>ID</sub> (diff p-p) after device configuration	—	—	—	2.2	—	—	2.2	—	—	2.2	V
Minimum differential eye opening at the receiver serial input pins <sup>(4)</sup>	—	85	—	—	85	—	—	85	—	—	mV
Differential on-chip termination resistors	85-Ω setting	—	85	—	—	85	—	—	85	—	Ω
	100-Ω setting	—	100	—	—	100	—	—	100	—	Ω
	120-Ω setting	—	120	—	—	120	—	—	120	—	Ω
	150-Ω setting	—	150	—	—	150	—	—	150	—	Ω
Differential and common mode return loss	PCIe Gen1, GIGE	Compliant									—
Programmable PPM detector <sup>(5)</sup>	—	±62.5, 100, 125, 200, 250, 300, 500, and 1000									ppm
Run Length	—	—	—	200	—	—	200	—	—	200	UI
Programmable equalization	—	—	—	4	—	—	4	—	—	4	dB
Programmable DC gain	DC Gain Setting = 0	—	0	—	—	0	—	—	0	—	dB
	DC Gain Setting = 1	—	3	—	—	3	—	—	3	—	dB

**Table 2-20. Transceiver Specifications for Cyclone V GX Devices—Preliminary (Part 3 of 3)**

Symbol/ Description	Conditions	C6 Speed Grade			C7, I7 Speed Grade			C8, A7 Speed Grade			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
<b>Transmitter</b>											
Supported I/O Standards	1.5 V PCML										
Data rate	—	614	—	3125	614	—	3125	614	—	2500	Mbps
V <sub>OCM</sub>	—	—	650	—	—	650	—	—	650	—	mV
Differential on-chip termination resistors	85-Ω setting	—	85	—	—	85	—	—	85	—	Ω
	100-Ω setting	—	100	—	—	100	—	—	100	—	Ω
	120-Ω setting	—	120	—	—	120	—	—	120	—	Ω
	150-Ω setting	—	150	—	—	150	—	—	150	—	Ω
Rise time <sup>(6)</sup>	—	30	—	160	30	—	160	30	—	160	ps
Fall time <sup>(6)</sup>	—	30	—	160	30	—	160	30	—	160	ps
<b>CMU PLL</b>											
Supported data range	—	614	—	3125	614	—	3125	614	—	2500	Mbps
<b>Transceiver-FPGA Fabric Interface</b>											
Interface speed (single-width mode)	—	25	—	187.5	25	—	163.84	25	—	156.25	MHz
Interface speed (double-width mode)	—	25	—	163.84	25	—	163.84	25	—	156.25	MHz

**Notes to Table 2-20:**

- (1) Differential LVPECL signal levels must comply to the minimum and maximum peak-to-peak differential input voltage specified in this table.
- (2) The reference clock common mode voltage is equal to the V<sub>CCR\_GXB</sub> power supply level.
- (3) The device cannot tolerate prolonged operation at this absolute maximum.
- (4) The differential eye opening specification at the receiver input pins assumes that you have disabled the Receiver Equalization feature. If you enable the Receiver Equalization feature, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.
- (5) The rate matcher supports only up to ±300 parts per million (ppm).
- (6) The Quartus II software automatically selects the appropriate slew rate depending on the configured data rate or functional mode.

Table 2–21 lists the Cyclone V GX transceiver block jitter specifications.

**Table 2–21. Transceiver Block Jitter Specifications for Cyclone V GX Devices—Preliminary**

Symbol/ Description	Conditions	C6 Speed Grade			C7, I7 Speed Grade			C8, A7 Speed Grade			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
<b>PCIe Transmit Jitter Generation <sup>(1)</sup></b>											
Total jitter at 2.5 Gbps (Gen1)	Compliance pattern	—	—	0.25	—	—	0.25	—	—	0.25	UI
<b>PCIe Receiver Jitter Tolerance <sup>(1)</sup></b>											
Total jitter at 2.5 Gbps (Gen1)	Compliance pattern	> 0.6			> 0.6			> 0.6			UI
<b>GIGE Transmit Jitter Generation <sup>(2)</sup></b>											
Deterministic jitter (peak-to-peak)	Pattern = CRPAT	—	—	0.14	—	—	0.14	—	—	0.14	UI
Total jitter (peak-to-peak)	Pattern = CRPAT	—	—	0.279	—	—	0.279	—	—	0.279	UI
<b>GIGE Receiver Jitter Tolerance <sup>(2)</sup></b>											
Deterministic jitter tolerance (peak-to-peak)	Pattern = CJPAT	> 0.4			> 0.4			> 0.4			UI
Combined deterministic and random jitter tolerance (peak-to-peak)	Pattern = CJPAT	> 0.66			> 0.66			> 0.66			UI

**Notes to Table 2–21:**

- (1) The jitter numbers for PIPE are compliant to the PCIe Base Specification 2.0.
- (2) The jitter numbers for GIGE are compliant to the IEEE802.3-2002 Specification.

## Core Performance Specifications

This section describes the clock tree, phase-locked loop (PLL), digital signal processing (DSP), and memory block specifications.

### Clock Tree Specifications

Table 2–22 lists the clock tree specifications for Cyclone V devices.

**Table 2–22. Clock Tree Performance for Cyclone V Devices—Preliminary**

Performance				Unit
Symbol	C6 Speed Grade	C7, I7 Speed Grade	C8, A7 Speed Grade	
Global clock and Regional clock	550	550	460	MHz
Peripheral clock	155	155	155	MHz

### PLL Specifications

Table 2–23 lists the Cyclone V PLL specifications when operating in the commercial (0° to 85°C), industrial (–40° to 100°C), and automotive (–40° to 125°C) junction temperature ranges.

**Table 2–23. PLL Specifications for Cyclone V Devices—Preliminary <sup>(1)</sup> (Part 1 of 3)**

Symbol	Parameter	Min	Typ	Max	Unit	
$f_{IN}$	Input clock frequency	C6 speed grade	5	—	670 <sup>(2)</sup>	MHz
		C7, I7 speed grades	5	—	622 <sup>(2)</sup>	MHz
		C8, A7 speed grades	5	—	500 <sup>(2)</sup>	MHz
$f_{INPFD}$	Integer input clock frequency to the PFD	5	—	325	MHz	
$f_{FINPFD}$	Fractional input clock frequency to the PFD	50	—	TBD <sup>(1)</sup>	MHz	
$f_{VCO}$	PLL VCO operating range	C6 speed grade	600	—	1600	MHz
		C7, I7 speed grades	600	—	1400	MHz
		C8, A7 speed grades	600	—	1300	MHz
$t_{EINDUTY}$	Input clock or external feedback clock input duty cycle	40	—	60	%	
$f_{OUT}$	Output frequency for internal global or regional clock	C6 speed grade	—	—	550 <sup>(3)</sup>	MHz
		C7, I7 speed grades	—	—	550 <sup>(3)</sup>	MHz
		C8, A7 speed grades	—	—	460 <sup>(3)</sup>	MHz
$f_{OUT\_EXT}$	Output frequency for external clock output	C6 speed grade	—	—	667 <sup>(3)</sup>	MHz
		C7, I7 speed grades	—	—	667 <sup>(3)</sup>	MHz
		C8, A7 speed grades	—	—	533 <sup>(3)</sup>	MHz
$t_{OUTDUTY}$	Duty cycle for external clock output (when set to 50%)	45	50	55	%	
$t_{FCOMP}$	External feedback clock compensation time	—	—	10	ns	
$t_{CONFIGPHASE}$	Time required to reconfigure phase shift	—	—	TBD <sup>(1)</sup>	—	
$t_{DYCONFIGCLK}$	Dynamic configuration clock	—	—	100	MHz	
$t_{LOCK}$	Time required to lock from end-of-device configuration or deassertion of <code>areset</code>	—	—	1	ms	

**Table 2-23. PLL Specifications for Cyclone V Devices—Preliminary <sup>(1)</sup> (Part 2 of 3)**

Symbol	Parameter	Min	Typ	Max	Unit
$t_{\text{DLOCK}}$	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/delays)	—	—	1	ms
$f_{\text{CLBW}}$	PLL closed-loop low bandwidth	—	0.3	—	MHz
	PLL closed-loop medium bandwidth	—	1.5	—	MHz
	PLL closed-loop high bandwidth <sup>(8)</sup>	—	4	—	MHz
$t_{\text{PLL\_PSERR}}$	Accuracy of PLL phase shift	—	—	±50	ps
$t_{\text{ARESET}}$	Minimum pulse width on the $\text{areset}$ signal	10	—	—	ns
$t_{\text{INCCJ}}$ <sup>(4), (5)</sup>	Input clock cycle-to-cycle jitter ( $F_{\text{REF}} \geq 100$ MHz)	—	—	0.15	UI (p-p)
	Input clock cycle-to-cycle jitter ( $F_{\text{REF}} < 100$ MHz)	—	—	±750	ps (p-p)
$t_{\text{OUTPJ\_DC}}$ <sup>(6)</sup>	Period jitter for dedicated clock output ( $F_{\text{OUT}} \geq 100$ MHz)	—	—	TBD <sup>(1)</sup>	ps (p-p)
	Period jitter for dedicated clock output ( $F_{\text{OUT}} < 100$ MHz)	—	—	TBD <sup>(1)</sup>	mUI (p-p)
$t_{\text{OUTCCJ\_DC}}$ <sup>(6)</sup>	Cycle-to-cycle jitter for dedicated clock output ( $F_{\text{OUT}} \geq 100$ MHz)	—	—	TBD <sup>(1)</sup>	ps (p-p)
	Cycle-to-cycle jitter for dedicated clock output ( $F_{\text{OUT}} < 100$ MHz)	—	—	TBD <sup>(1)</sup>	mUI (p-p)
$t_{\text{OUTPJ\_IO}}$ <sup>(6), (9)</sup>	Period jitter for clock output on regular I/O ( $F_{\text{OUT}} \geq 100$ MHz)	—	—	TBD <sup>(1)</sup>	ps (p-p)
	Period jitter for clock output on regular I/O ( $F_{\text{OUT}} < 100$ MHz)	—	—	TBD <sup>(1)</sup>	mUI (p-p)
$t_{\text{OUTCCJ\_IO}}$ <sup>(6), (9)</sup>	Cycle-to-cycle jitter for clock output on regular I/O ( $F_{\text{OUT}} \geq 100$ MHz)	—	—	TBD <sup>(1)</sup>	ps (p-p)
	Cycle-to-cycle jitter for clock output on regular I/O ( $F_{\text{OUT}} < 100$ MHz)	—	—	TBD <sup>(1)</sup>	mUI (p-p)
$t_{\text{OUTPJ\_DC\_F}}$	Period jitter for dedicated clock output in fractional mode	—	—	TBD <sup>(1)</sup>	—
$t_{\text{OUTCCJ\_DC\_F}}$	Cycle-to-cycle jitter for dedicated clock output in fractional mode	—	—	TBD <sup>(1)</sup>	—
$t_{\text{OUTPJ\_IO\_F}}$	Period jitter for clock output on regular I/O in fractional mode	—	—	TBD <sup>(1)</sup>	—
$t_{\text{OUTCCJ\_IO\_F}}$	Cycle-to-cycle jitter for clock output on regular I/O in fractional mode	—	—	TBD <sup>(1)</sup>	—
$t_{\text{CASC\_OUTPJ\_DC}}$ <sup>(6), (7)</sup>	Period jitter for dedicated clock output in cascaded PLLs ( $F_{\text{OUT}} \geq 100$ MHz)	—	—	TBD <sup>(1)</sup>	ps (p-p)
	Period jitter for dedicated clock output in cascaded PLLs ( $F_{\text{OUT}} < 100$ MHz)	—	—	TBD <sup>(1)</sup>	mUI (p-p)

**Table 2-23. PLL Specifications for Cyclone V Devices—Preliminary <sup>(7)</sup> (Part 3 of 3)**

Symbol	Parameter	Min	Typ	Max	Unit
$t_{\text{DRIFT}}$	Frequency drift after PFDENA is disabled for a duration of 100 $\mu\text{s}$	—	—	$\pm 10$	%
$dK_{\text{BIT}}$	Bit number of Delta Sigma Modulator (DSM)	—	24	—	Bits
$k_{\text{VALUE}}$	Numerator of Fraction	TBD <sup>(7)</sup>	8388608	TBD <sup>(7)</sup>	—
$f_{\text{RES}}$	Resolution of VCO frequency ( $f_{\text{INPFD}} = 100 \text{ MHz}$ )	—	5.96	—	Hz

**Notes to Table 2-23:**

- (1) Pending silicon characterization.
- (2) This specification is limited in the Quartus II software by the I/O maximum frequency. The maximum I/O frequency is different for each I/O standard.
- (3) This specification is limited by the lower of the two: I/O  $f_{\text{MAX}}$  or  $F_{\text{OUT}}$  of the PLL.
- (4) A high input jitter directly affects the PLL output jitter. To have low PLL output clock jitter, you must provide a clean clock source < 120 ps.
- (5)  $F_{\text{REF}}$  is  $f_{\text{IN}/N}$  when  $N = 1$ .
- (6) Peak-to-peak jitter with a probability level of  $10^{-12}$  (14 sigma, 99.9999999974404% confidence level). The output jitter specification applies to the intrinsic jitter of the PLL, when an input jitter of 30 ps is applied. The external memory interface clock output jitter specifications use a different measurement method and are available in [Table 2-28 on page 2-24](#).
- (7) The cascaded PLL specification is only applicable with the following condition:
  - a. Upstream PLL:  $0.59 \text{ MHz} \leq \text{Upstream PLL BW} < 1 \text{ MHz}$
  - b. Downstream PLL:  $\text{Downstream PLL BW} > 2 \text{ MHz}$
- (8) High bandwidth PLL settings are not supported in external feedback mode.
- (9) External memory interface clock output jitter specifications use a different measurement method, which is available in [Table 2-28 on page 2-24](#).

**DSP Block Specifications**

[Table 2-24](#) lists the Cyclone V DSP block performance specifications.

**Table 2-24. DSP Block Performance Specifications for Cyclone V Devices—Preliminary**

Mode	Performance			Unit
	C6 Speed Grade	C7, I7 Speed Grade	C8, A7 Speed Grade	
<b>Modes using One DSP Block</b>				
Independent 9 x 9 Multiplication	340	300	260	MHz
Independent 18 x 19 Multiplication	287	250	200	MHz
Independent 18 x 18 Multiplication	287	250	200	MHz
Independent 27 x 27 Multiplication	250	200	160	MHz
Independent 18 x 25 Multiplication	310	250	200	MHz
Independent 20 x 24 Multiplication	310	250	200	MHz
Two 18 x 19 Multiplier Adder Mode	310	250	200	MHz
18 x 18 Multiplier Added Summed with 36-bit Input	310	250	200	MHz
<b>Modes using Two DSP Blocks</b>				
Complex 18 x 19 multiplication	310	250	200	MHz
Two 27 x 27 Multiplier Adder	250	200	160	MHz
Four 18 x 19 Multiplier Adder	310	250	200	MHz



## Memory Block Specifications

Table 2–25 lists the Cyclone V memory block specifications.

**Table 2–25. Memory Block Performance Specifications for Cyclone V Devices—Preliminary <sup>(1)</sup>, <sup>(2)</sup>**

Memory	Mode	Resources Used		Performance			Unit
		ALUTs	Memory	C6 Speed Grade	C7, I7 Speed Grade	C8, A7 Speed Grade	
MLAB	Single port, all supported widths	0	1	450	380	330	MHz
	Simple dual-port, all supported widths	0	1	450	380	330	MHz
	Simple dual-port with read and write at the same address	0	1	350	300	250	MHz
	ROM, all supported width	0	1	450	380	330	MHz
M10K Block	Single-port, all supported widths	0	1	315	275	240	MHz
	Simple dual-port, all supported widths	0	1	315	275	240	MHz
	Simple dual-port with the <b>read-during-write</b> option set to <b>Old Data</b> , all supported widths	0	1	275	240	180	MHz
	True dual port, all supported widths	0	1	315	275	240	MHz
	ROM, all supported widths	0	1	315	275	240	MHz
	Min Pulse Width (clock high time)	—	—	1,450	1,550	1,650	ps
	Min Pulse Width (clock low time)	—	—	1,000	1,200	1,350	ps

**Notes to Table 2–25:**

- (1) To achieve the maximum memory block performance, use a memory block clock that comes through global clock routing from an on-chip PLL set to **50%** output duty cycle. Use the Quartus II software to report timing for this and other memory block clocking schemes.
- (2) When you use the error detection cyclical redundancy check (CRC) feature, there is no degradation in  $f_{MAX}$ .

## Periphery Performance

This section describes periphery performance and the high-speed I/O and external memory interface.

I/O performance supports several system interfaces, such as the LVDS high-speed I/O interface, external memory interface, and the PCI/PCI-X bus interface.

General-purpose I/O standards such as 3.3-, 2.5-, 1.8-, and 1.5-V **LVTTTL/LVCMOS** are capable of a typical 167 MHz and 1.2 **LVCMOS** at 100 MHz interfacing frequency with 10 pF load.



Actual achievable frequency depends on design- and system-specific factors. You must perform HSPICE/IBIS simulations based on your specific design and system setup to determine the maximum achievable frequency in your system.

## High-Speed I/O Specification

Table 2–26 lists high-speed I/O timing for Cyclone V devices.

**Table 2–26. High-Speed I/O Specifications for Cyclone V Devices—Preliminary (2), (3) (Part 1 of 2)**

Symbol	Conditions	C6 Speed Grade			C7, I7 Speed Grade			C8, A7 Speed Grade			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$f_{\text{HCLK\_in}}$ (input clock frequency) True Differential I/O Standards	Clock boost factor W = 1 to 40 (4)	5	—	437.5	5	—	420	5	—	320	MHz
$f_{\text{HCLK\_in}}$ (input clock frequency) Single Ended I/O Standards	Clock boost factor W = 1 to 40 (4)	5	—	320	5	—	320	5	—	275	MHz
$f_{\text{HCLK\_OUT}}$ (output clock frequency)	—	5	—	420	5	—	370	5	—	320	MHz
<b>Transmitter</b>											
True Differential I/O Standards - $f_{\text{HSDR}}$ (data rate)	SERDES factor J = 4 to 10	(5)	—	840	(5)	—	740	(5)	—	640	Mbps
	SERDES factor J = 1 to 2, Uses DDR Registers	(5)	—	(7)	(5)	—	(7)	(5)	—	(7)	Mbps
Emulated Differential I/O Standards with Three External Output Resistor Networks - $f_{\text{HSDR}}$ (data rate) (6)	SERDES factor J = 4 to 10	(5)	—	640	(5)	—	640	(5)	—	550	Mbps
Emulated Differential I/O Standards with One External Output Resistor Network - $f_{\text{HSDR}}$ (data rate) (6)	SERDES factor J = 4 to 10	(5)	—	170	(5)	—	170	(5)	—	170	Mbps
$t_{\text{x Jitter}}$ - True Differential I/O Standards	Total Jitter for Data Rate, 600 Mbps - 840 Mbps	—	—	160	—	—	160	—	—	160	ps
	Total Jitter for Data Rate, < 600 Mbps	—	—	0.1	—	—	0.1	—	—	0.1	UI
$t_{\text{x Jitter}}$ - Emulated Differential I/O Standards with Three External Output Resistor Networks	Total Jitter for Data Rate < 640 Mbps	—	—	TBD (1)	—	—	TBD (1)	—	—	TBD (1)	UI
$t_{\text{x Jitter}}$ - Emulated Differential I/O Standards with One External Output Resistor Network	Total Jitter for Data Rate < 640 Mbps	—	—	TBD (1)	—	—	TBD (1)	—	—	TBD (1)	UI

**Table 2-26. High-Speed I/O Specifications for Cyclone V Devices—Preliminary (2), (3) (Part 2 of 2)**

Symbol	Conditions	C6 Speed Grade			C7, I7 Speed Grade			C8, A7 Speed Grade			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$t_{DUTY}$	TX output clock duty cycle for both True and Emulated Differential I/O Standards	45	50	55	45	50	55	45	50	55	%
$t_{RISE}$ & $t_{FALL}$	True Differential I/O Standards	—	—	200	—	—	200	—	—	200	ps
	Emulated Differential I/O Standards with Three External Output Resistor Networks	—	—	250	—	—	250	—	—	300	ps
	Emulated Differential I/O Standards with One External Output Resistor Network	—	—	300	—	—	300	—	—	300	ps
TCCS	True Differential I/O Standards	—	—	200	—	—	250	—	—	250	ps
	Emulated Differential I/O Standards with Three External Output Resistor Networks	—	—	300	—	—	300	—	—	300	ps
	Emulated Differential I/O Standards with One External Output Resistor Network	—	—	300	—	—	300	—	—	300	ps
<b>Receiver</b>											
$f_{HSDR}$ (data rate)	SERDES factor J = 4 to 10	(5)	—	875 (6)	(5)	—	840 (6)	(5)	—	640 (6)	Mbps
	SERDES factor J = 1 to 2, Uses DDR Registers	(5)	—	(7)	(5)	—	(7)	(5)	—	(7)	Mbps
Sampling Window	—	—	—	350	—	—	350	—	—	350	ps

**Notes to Table 2-26:**

- (1) Pending silicon characterization.
- (2) When J = 1 or 2, bypass the serializer/deserializer (SERDES) block.
- (3) This is achieved by using the LVDS clock network.
- (4) Clock Boost Factor (W) is the ratio between the input data rate and the input clock rate.
- (5) The minimum specification depends on the clock source (for example, the PLL and clock pin) and the clock routing resource (global, regional, or local) that you use. The I/O differential buffer and input register do not have a minimum toggle rate.
- (6) You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and receiver sampling margin to determine the leftover timing margin.
- (7) The maximum ideal frequency is the SERDES factor (J) x PLL max output frequency ( $f_{out}$ ), provided you can close the design timing and the signal integrity simulation is clean. You can estimate the achievable maximum data rate by performing link timing closure analysis. You must consider the board skew margin, transmitter delay margin, and receiver sampling margin to determine the maximum data rate supported.

## DQS Logic Block and Memory Output Clock Jitter Specifications

Table 2–27 lists the DQS phase shift error for Cyclone V devices.

**Table 2–27. DQS Phase Shift Error Specification for DLL-Delayed Clock ( $t_{DQS\_PSERR}$ ) for Cyclone V Devices—Preliminary (1), (2)**

Number of DQS Delay Buffers	C6 Speed Grade	C7, I7 Speed Grade	C8, A7 Speed Grade	Unit
2	69	70	80	ps

**Notes to Table 2–27:**

- (1) The numbers are preliminary pending silicon characterization.
- (2) This error specification is the absolute maximum and minimum error. For example, skew on two DQS delay buffers in a –7 speed grade is 70 ps or  $\pm 35$  ps.
- (3) Delay chain engineering option setting: `rb_co[1:0]="11"`.

Table 2–28 lists the memory output clock jitter specifications for Cyclone V devices.

**Table 2–28. Memory Output Clock Jitter Specification for Cyclone V Devices—Preliminary (1), (2), (3)**

Parameter	Clock Network	Symbol	C6 Speed Grade		C7, I7 Speed Grade		C8, A7 Speed Grade		Unit
			Min	Max	Min	Max	Min	Max	
Clock period jitter	Regional	$t_{JIT(per)}$	TBD	TBD	TBD	TBD	TBD	TBD	ps
Cycle-to-cycle period jitter	Regional	$t_{JIT(cc)}$	TBD	TBD	TBD	TBD	TBD	TBD	ps
Duty cycle jitter	Regional	$t_{JIT(duty)}$	TBD	TBD	TBD	TBD	TBD	TBD	ps
Clock period jitter	Global	$t_{JIT(per)}$	TBD	TBD	TBD	TBD	TBD	TBD	ps
Cycle-to-cycle period jitter	Global	$t_{JIT(cc)}$	TBD	TBD	TBD	TBD	TBD	TBD	ps
Duty cycle jitter	Global	$t_{JIT(duty)}$	TBD	TBD	TBD	TBD	TBD	TBD	ps

**Notes to Table 2–28:**

- (1) Pending silicon characterization.
- (2) The memory output clock jitter measurements are for 200 consecutive clock cycles, as specified in the JEDEC DDR2/DDR3 SDRAM standard.
- (3) The clock jitter specification applies to the memory output clock pins generated using differential signal-splitter and DDIO circuits clocked by a PLL output routed on a PHY, regional, or global clock network as specified. Altera recommends using PHY clock networks whenever possible.

## OCT Calibration Block Specifications

Table 2–29 lists the OCT calibration block specifications for Cyclone V devices.

**Table 2–29. OCT Calibration Block Specifications for Cyclone V Devices—Preliminary (Part 1 of 2)**

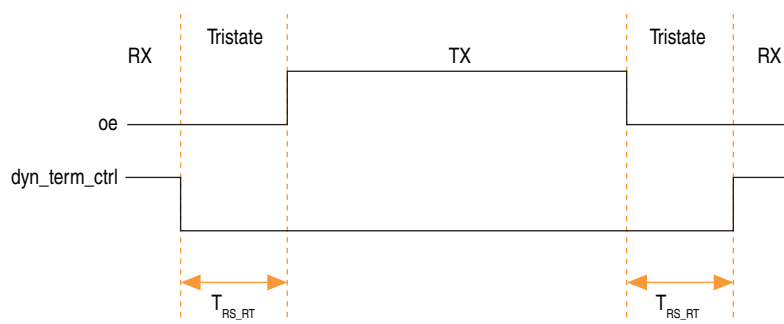
Symbol	Description	Min	Typ	Max	Unit
OCTUSRCLK	Clock required by OCT calibration blocks	—	—	20	MHz
$T_{OCTCAL}$	Number of OCTUSRCLK clock cycles required for $R_S$ OCT / $R_T$ OCT calibration	—	1000	—	Cycles

**Table 2-29. OCT Calibration Block Specifications for Cyclone V Devices—Preliminary (Part 2 of 2)**

Symbol	Description	Min	Typ	Max	Unit
$T_{\text{OCTSHIFT}}$	Number of OCTUSRCLK clock cycles required for OCT code to shift out	—	32	—	Cycles
$T_{\text{RS\_RT}}$	Time required between the <code>dyn_term_ctrl</code> and <code>oe</code> signal transitions in a bidirectional I/O buffer to dynamically switch between $R_S$ OCT and $R_T$ OCT	—	2.5	—	ns

Figure 2-1 shows the timing diagram for the `oe` and `dyn_term_ctrl` signals.

**Figure 2-1. Timing Diagram for the `oe` and `dyn_term_ctrl` Signals**



### Duty Cycle Distortion (DCD) Specifications

Table 2-30 lists the worst-case DCD for Cyclone V devices.

**Table 2-30. Worst-Case DCD on I/O Pins for Cyclone V Devices—Preliminary**

Symbol	C6 Speed Grade		C7, I7 Speed Grade		C8, A7 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
Output Duty Cycle	45	55	45	55	45	55	%

## Configuration Specification

This section provides configuration specifications and timing for Cyclone V devices. These characteristics can be designated as preliminary or final.

- Preliminary characteristics are obtained using simulation results, process data, and other known parameters. The title of these tables show the designation as “Preliminary.”
- Final numbers are based on actual silicon characterization and testing. The numbers reflect the actual performance of the device under worst-case silicon process, voltage, and junction temperature conditions. There are no designations on finalized tables.

### POR Specifications

Table 2–31 lists the specifications for fast and standard POR delay for Cyclone V devices.

**Table 2–31. Fast and Standard POR Delay Specification for Cyclone V Devices**

POR Delay	PORSEL Pin Setting	Minimum (ms)	Maximum (ms)
Fast <sup>(1)</sup>	High	4	12
Standard	GND	100	300

**Note to Table 2–31:**

- (1) The maximum pulse width of the fast POR delay is 12 ms, providing enough time for the PCIe hard IP to initialize after the POR trip.

### JTAG Configuration Timing

Table 2–32 lists the JTAG timing parameters and values for Cyclone V devices.

**Table 2–32. JTAG Timing Parameters and Values for Cyclone V Devices—Preliminary**

Symbol	Description	Min	Max	Unit
$t_{JCP}$	TCK clock period	30	—	ns
$t_{JCH}$	TCK clock high time	14	—	ns
$t_{JCL}$	TCK clock low time	14	—	ns
$t_{JPSU(TDI)}$	TDI JTAG port setup time	1	—	ns
$t_{JPSU(TMS)}$	TMS JTAG port setup time	3	—	ns
$t_{JPH}$	JTAG port hold time	5	—	ns
$t_{JPCO}$	JTAG port clock to output	—	11 <sup>(1)</sup>	ns
$t_{JPZX}$	JTAG port high impedance to valid output	—	14 <sup>(1)</sup>	ns
$t_{JPXZ}$	JTAG port valid output to high impedance	—	14 <sup>(1)</sup>	ns

**Note to Table 2–32:**

- (1) A 1 ns adder is required for each  $V_{CCIO}$  voltage step down from 3.0 V. For example,  $t_{JPCO} = 12$  ns if  $V_{CCIO}$  of the TDO I/O bank = 2.5 V, or 13 ns if it equals 1.8 V.

## FPP Configuration Timing

This section describes the fast passive parallel (FPP) configuration timing parameters for Cyclone V devices.

### DCLK-to-DATA[] Ratio (r) for FPP Configuration

FPP configuration requires a different DCLK-to-DATA[] ratio when you turn on encryption or the compression feature.

Table 2–33 lists the DCLK-to-DATA[] ratio for each combination.

**Table 2–33. DCLK-to-DATA[] Ratio for Cyclone V Devices—Preliminary <sup>(1)</sup>**

Configuration Scheme	Encryption	Compression	DCLK-to-DATA[] ratio (r)
FPP (8-bit wide)	Off	Off	1
	On	Off	1
	Off	On	2
	On	On	2
FPP (16-bit wide)	Off	Off	1
	On	Off	2
	Off	On	4
	On	On	4

**Note to Table 2–33:**

- (1) Depending on the DCLK-to-DATA[] ratio, the host must send a DCLK frequency that is r times the DATA[] rate in byte per second (Bps) or word per second (Wps). For example, in FPP x16 where the r is 2, the DCLK frequency must be 2 times the DATA[] rate in Wps.

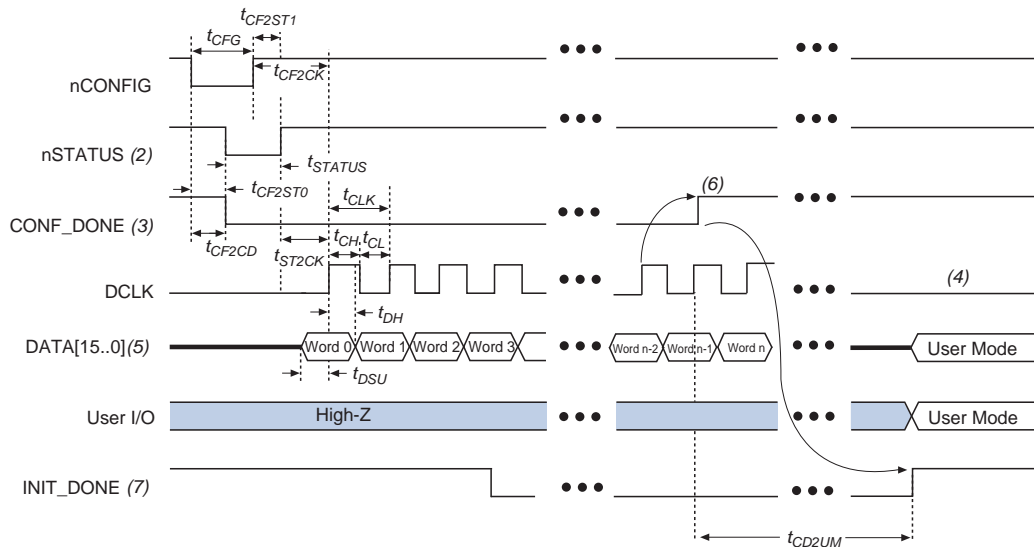
## FPP Configuration Timing when DCLK to DATA[] = 1

Figure 2-2 shows the timing waveform for an FPP configuration when using a MAX<sup>®</sup> II device as an external host. This waveform shows timing when the DCLK-to-DATA[] ratio is 1.



When you enable decompression or the design security feature, the DCLK-to-DATA[] ratio varies for FPP x8 and FPP x16. For the respective DCLK-to-DATA[] ratio, refer to Table 2-33 on page 2-27.

**Figure 2-2. DCLK-to-DATA[] FPP Configuration Timing Waveform for Cyclone V Devices When the Ratio is 1 <sup>(1)</sup>**



### Notes to Figure 2-2:

- (1) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF\_DONE are at logic-high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (2) After power up, the Cyclone V device holds nSTATUS low for the time of the POR delay.
- (3) After power up, before and during configuration, CONF\_DONE is low.
- (4) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (5) For FPP x16, use DATA[15..0]. For FPP x8, use DATA[7..0]. DATA[15..0] are available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings.
- (6) To ensure a successful configuration, send the entire configuration data to the Cyclone V device. CONF\_DONE is released high when the Cyclone V device receives all the configuration data successfully. After CONF\_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (7) After the option bit to enable the INIT\_DONE pin is configured into the device, INIT\_DONE goes low.



Table 2–34 lists the timing parameters for Cyclone V devices for an FPP configuration when the DCLK-to-DATA[ ] ratio is 1.

**Table 2–34. DCLK-to-DATA[ ] FPP Timing Parameters for Cyclone V Devices When the Ratio is 1—Preliminary <sup>(1)</sup>**

Symbol	Parameter	Minimum	Maximum	Unit
$t_{CF2CD}$	nCONFIG low to CONF_DONE low	—	600	ns
$t_{CF2ST0}$	nCONFIG low to nSTATUS low	—	600	ns
$t_{CFG}$	nCONFIG low pulse width	2	—	$\mu$ s
$t_{STATUS}$	nSTATUS low pulse width	268	1506 <sup>(2)</sup>	$\mu$ s
$t_{CF2ST1}$	nCONFIG high to nSTATUS high	—	1506 <sup>(3)</sup>	$\mu$ s
$t_{CF2CK}$	nCONFIG high to first rising edge on DCLK	1506	—	$\mu$ s
$t_{ST2CK}$	nSTATUS high to first rising edge of DCLK	2	—	$\mu$ s
$t_{DSU}$	DATA[ ] setup time before rising edge on DCLK	5.5	—	ns
$t_{DH}$	DATA[ ] hold time after rising edge on DCLK	0	—	ns
$t_{CH}$	DCLK high time	$0.45 \times 1/f_{MAX}$	—	ns
$t_{CL}$	DCLK low time	$0.45 \times 1/f_{MAX}$	—	ns
$t_{CLK}$	DCLK period	$1/f_{MAX}$	—	ns
$f_{MAX}$	DCLK frequency (FPP x8 and x16)	—	125	MHz
$t_R$	Input rise time	—	40	ns
$t_F$	Input fall time	—	40	ns
$t_{CD2UM}$	CONF_DONE high to user mode <sup>(4)</sup>	175	437	$\mu$ s
$t_{CD2CU}$	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	—
$t_{CD2UMC}$	CONF_DONE high to user mode with CLKUSR option on	$t_{CD2CU} + (T_{init} \times \text{CLKUSR period})$	—	—
$T_{init}$	Number of clock cycles required for device initialization	17,408	—	Cycles

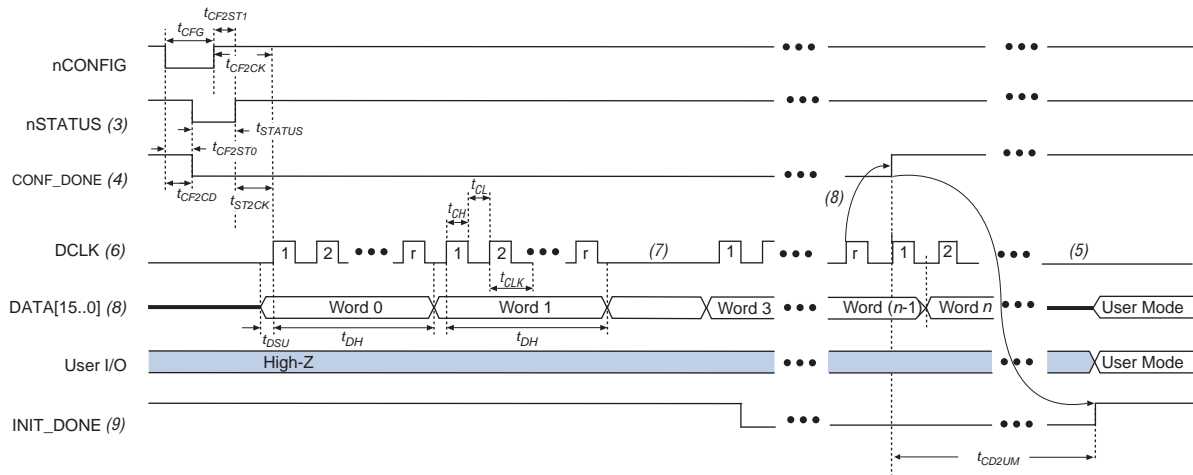
**Notes to Table 2–34:**

- (1) Use these timing parameters when the DCLK-to-DATA[ ] ratio is 1. To find the DCLK-to-DATA[ ] ratio for your system, refer to Table 2–33 on page 2–27.
- (2) You can obtain this value if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
- (3) You can obtain this value if you do not delay configuration by externally holding nSTATUS low.
- (4) The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.

## FPP Configuration Timing when DCLK to DATA[] > 1

Figure 2-3 shows the timing waveform for an FPP configuration when using a MAX II device or microprocessor as an external host. This waveform shows timing when the DCLK-to-DATA[] ratio is more than 1.

**Figure 2-3. FPP Configuration Timing Waveform for Cyclone V Devices When the DCLK-to-DATA[] Ratio is > 1 (1), (2)**



### Notes to Figure 2-3:

- (1) To find the DCLK-to-DATA[] ratio for your system, refer to Table 2-33 on page 2-27.
- (2) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF\_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (3) After power up, the Cyclone V device holds nSTATUS low for the time as specified by the POR delay.
- (4) After power up, before and during configuration, CONF\_DONE is low.
- (5) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (6) "r" denotes the DCLK-to-DATA[] ratio. For the DCLK-to-DATA[] ratio based on the decompression and the design security feature enable settings, refer to Table 2-33 on page 2-27.
- (7) If needed, pause DCLK by holding it low. When DCLK restarts, the external host must provide data on the DATA[15..0] pins prior to sending the first DCLK rising edge.
- (8) To ensure a successful configuration, send the entire configuration data to the Cyclone V device. CONF\_DONE is released high after the Cyclone V device receives all the configuration data successfully. After CONF\_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (9) After the option bit to enable the INIT\_DONE pin is configured into the device, INIT\_DONE goes low.

Table 2–35 lists the timing parameters for Cyclone V devices when the DCLK-to-DATA[ ] ratio is more than 1.

**Table 2–35. DCLK-to-DATA[ ] FPP Timing Parameters for Cyclone V Devices when the Ratio is > 1—Preliminary <sup>(1)</sup>**

Symbol	Parameter	Minimum	Maximum	Unit
$t_{CF2CD}$	nCONFIG low to CONF_DONE low	—	600	ns
$t_{CF2ST0}$	nCONFIG low to nSTATUS low	—	600	ns
$t_{CFG}$	nCONFIG low pulse width	2	—	$\mu$ s
$t_{STATUS}$	nSTATUS low pulse width	268	1506 <sup>(2)</sup>	$\mu$ s
$t_{CF2ST1}$	nCONFIG high to nSTATUS high	—	1506 <sup>(3)</sup>	$\mu$ s
$t_{CF2CK}$	nCONFIG high to first rising edge on DCLK	1506	—	$\mu$ s
$t_{ST2CK}$	nSTATUS high to first rising edge of DCLK	2	—	$\mu$ s
$t_{DSU}$	DATA[ ] setup time before rising edge on DCLK	5.5	—	ns
$t_{DH}$	DATA[ ] hold time after rising edge on DCLK	$N-1/f_{DCLK}$ <sup>(4)</sup>	—	ns
$t_{CH}$	DCLK high time	$0.45 \times 1/f_{MAX}$	—	ns
$t_{CL}$	DCLK low time	$0.45 \times 1/f_{MAX}$	—	ns
$t_{CLK}$	DCLK period	$1/f_{MAX}$	—	ns
$f_{MAX}$	DCLK frequency (FPP x8 and x16)	—	125	MHz
$t_R$	Input rise time	—	40	ns
$t_F$	Input fall time	—	40	ns
$t_{CD2UM}$	CONF_DONE high to user mode <sup>(5)</sup>	175	437	$\mu$ s
$t_{CD2CU}$	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	—
$t_{CD2UMC}$	CONF_DONE high to user mode with CLKUSR option on	$t_{CD2CU} + (T_{init} \times CLKUSR \text{ period})$	—	—
$T_{init}$	Number of clock cycles required for device initialization	17,408	—	Cycles

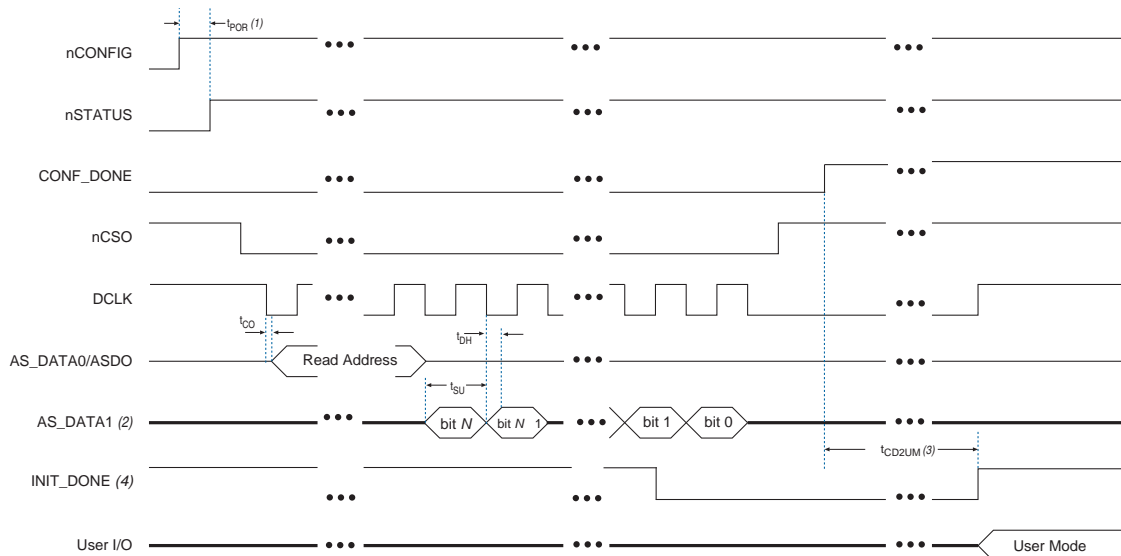
**Notes to Table 2–35:**

- (1) Use these timing parameters when you use decompression and the design security features.
- (2) This value can be obtained if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
- (3) This value can be obtained if you do not delay configuration by externally holding nSTATUS low.
- (4) N is the DCLK-to-DATA ratio and  $f_{DCLK}$  is the DCLK frequency the system is operating.
- (5) The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.

## AS Configuration Timing

Figure 2-4 shows the timing waveform for the active serial (AS) x1 mode and AS x4 mode configuration timing.

Figure 2-4. AS Configuration Timing for Cyclone V Devices



### Notes to Figure 2-4:

- (1) The AS scheme supports standard and fast POR delay ( $t_{POR}$ ). For  $t_{POR}$  delay information, refer to “POR Delay Specification” in the *Configuration, Design Security, and remote System Upgrades in Cyclone V Devices* chapter.
- (2) If you are using AS x4 mode, this signal represents the AS\_DATA[3..0] and EPCQ sends in 4-bits of data for each DCLK cycle.
- (3) The initialization clock can be from the internal oscillator or the CLKUSR pin.
- (4) After the option bit to enable the INIT\_DONE pin is configured into the device, INIT\_DONE goes low.

Table 2-36 lists the timing parameters for AS x1 and AS x4 configurations in Cyclone V devices.

Table 2-36. AS Timing Parameters for AS x1 and x4 Configurations in Cyclone V Devices—Preliminary (1), (2)

Symbol	Parameter	Minimum	Maximum	Unit
$t_{CO}$	DCLK falling edge to the AS_DATA0/ASDO output	—	4	$\mu$ S
$t_{SU}$	Data setup time before the rising edge on DCLK	1.5	—	ns
$t_H$	Data hold time after the rising edge on DCLK	0	—	ns
$t_{CD2UM}$	CONF_DONE high to user mode	175	437	$\mu$ S
$t_{CD2CU}$	CONF_DONE high to CLKUSR enabled	4 x maximum DCLK period	—	—
$t_{CD2UMC}$	CONF_DONE high to user mode with CLKUSR option on	$t_{CD2CU} + (T_{init} \times \text{CLKUSR period})$	—	—
$T_{init}$	Number of clock cycles required for device initialization	17,408	—	Cycles

### Notes to Table 2-36:

- (1) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.
- (2) The  $t_{CF2CD}$ ,  $t_{CF2ST0}$ ,  $t_{CFG}$ ,  $t_{STATUS}$ , and  $t_{CF2ST1}$  timing parameters are identical to the timing parameters for passive serial (PS) mode listed in Table 2-38 on page 2-34.

Table 2-37 lists the internal clock frequency specification for the AS configuration scheme.

**Table 2-37. DCLK Frequency Specification in the AS Configuration Scheme for Cyclone V Devices—Preliminary (1), (2)**

Minimum	Typical	Maximum	Unit
5.3	7.9	12.5	MHz
10.6	15.7	25.0	MHz
21.3	31.4	50.0	MHz
42.6	62.9	100.0	MHz

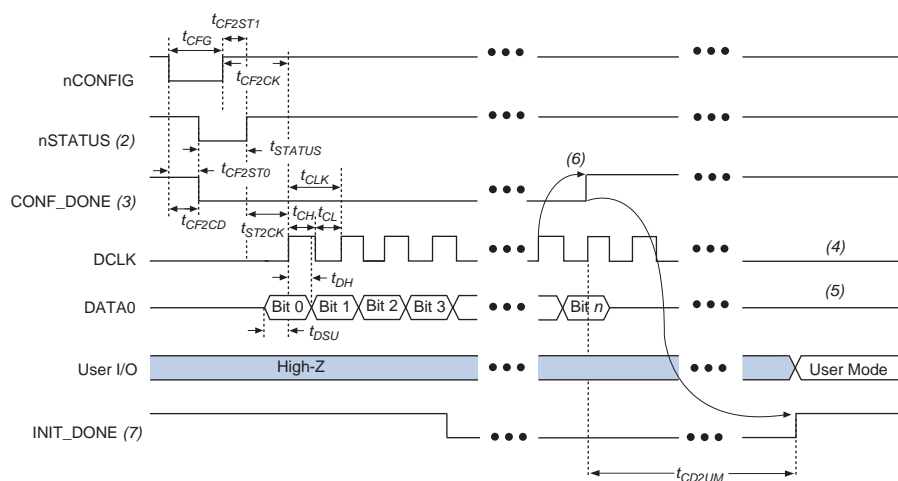
**Notes to Table 2-37:**

- (1) This applies to the DCLK frequency specification when using the internal oscillator as the configuration clock source.
- (2) The AS multi-device configuration scheme does not support DCLK frequency of 100 MHz.

## PS Configuration Timing

Figure 2-5 shows the timing waveform for a PS configuration when using a MAX II device or microprocessor as an external host.

**Figure 2-5. PS Configuration Timing Waveform for Cyclone V Devices (1)**



**Notes to Figure 2-5:**

- (1) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF\_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (2) After power up, the Cyclone V device holds nSTATUS low for the time of the POR delay.
- (3) After power up, before and during configuration, CONF\_DONE is low.
- (4) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (5) DATA0 is available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings in the **Device and Pins Option**.
- (6) To ensure a successful configuration, send the entire configuration data to the Cyclone V device. CONF\_DONE is released high after the Cyclone V device receives all the configuration data successfully. After CONF\_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (7) After the option bit to enable the INIT\_DONE pin is configured into the device, INIT\_DONE goes low.

Table 2–38 lists the PS timing parameter for Cyclone V devices.

**Table 2–38. PS Timing Parameters for Cyclone V Devices—Preliminary**

Symbol	Parameter	Minimum	Maximum	Unit
$t_{CF2CD}$	nCONFIG low to CONF_DONE low	—	600	ns
$t_{CF2ST0}$	nCONFIG low to nSTATUS low	—	600	ns
$t_{CFG}$	nCONFIG low pulse width	2	—	$\mu$ s
$t_{STATUS}$	nSTATUS low pulse width	268	1506 <sup>(1)</sup>	$\mu$ s
$t_{CF2ST1}$	nCONFIG high to nSTATUS high	—	1506 <sup>(2)</sup>	$\mu$ s
$t_{CF2CK}$	nCONFIG high to first rising edge on DCLK	1506	—	$\mu$ s
$t_{ST2CK}$	nSTATUS high to first rising edge of DCLK	2	—	$\mu$ s
$t_{DSU}$	DATA[ ] setup time before rising edge on DCLK	5.5	—	ns
$t_{DH}$	DATA[ ] hold time after rising edge on DCLK	0	—	ns
$t_{CH}$	DCLK high time	$0.45 \times 1/f_{MAX}$	—	ns
$t_{CL}$	DCLK low time	$0.45 \times 1/f_{MAX}$	—	ns
$t_{CLK}$	DCLK period	$1/f_{MAX}$	—	ns
$f_{MAX}$	DCLK frequency	—	125	MHz
$t_R$	Input rise time	—	40	ns
$t_F$	Input fall time	—	40	ns
$t_{CD2UM}$	CONF_DONE high to user mode <sup>(3)</sup>	175	437	$\mu$ s
$t_{CD2CU}$	CONF_DONE high to CLKUSR enabled	4 x maximum DCLK period	—	—
$t_{CD2UMC}$	CONF_DONE high to user mode with CLKUSR option on	$t_{CD2CU} + (T_{init} \times CLKUSR \text{ period})$	—	—
$T_{init}$	Number of clock cycles required for device initialization	17,408	—	Cycles

**Notes to Table 2–38:**

- (1) You can obtain this value if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
- (2) You can obtain this value if you do not delay configuration by externally holding nSTATUS low.
- (3) The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.

## Remote System Upgrades Circuitry Timing Specification

Table 2–39 lists the timing parameter specifications for the remote system upgrade circuitry.

**Table 2–39. Remote System Upgrade Circuitry Timing Specification for Cyclone V Devices—Preliminary**

Parameter	Minimum	Maximum	Unit
$t_{\text{MAX\_RU\_CLK}}^{(1)}$	—	40	MHz
$t_{\text{RU\_nCONFIG}}^{(2)}$	250	—	ns
$t_{\text{RU\_nRSTIMER}}^{(3)}$	250	—	ns

**Notes to Table 2–39:**

- (1) This clock is user-supplied to the remote system upgrade circuitry. If you are using the ALTREMOTE\_UPDATE megafunction, the clock user-supplied to the ALTREMOTE\_UPDATE megafunction must meet this specification.
- (2) This is equivalent to strobing the reconfiguration input of the ALTREMOTE\_UPDATE megafunction high for the minimum timing specification. For more information, refer to “Remote System Upgrade State Machine” in the *Device Interfaces and Integration Basics for Cyclone V Devices* chapter.
- (3) This is equivalent to strobing the reset timer input of the ALTREMOTE\_UPDATE megafunction high for the minimum timing specification. For more information, refer to “User Watchdog Timer” in the *Device Interfaces and Integration Basics for Cyclone V Devices* chapter.

## User Watchdog Internal Oscillator Frequency Specification

Table 2–40 lists the frequency specifications for the user watchdog internal oscillator.

**Table 2–40. User Watchdog Internal Oscillator Frequency Specifications for Cyclone V Devices—Preliminary**

Minimum	Typical	Maximum	Unit
5.3	7.9	12.5	MHz

## I/O Timing

Altera offers two ways to determine I/O timing—the Excel-based I/O Timing and the Quartus II Timing Analyzer.

Excel-based I/O timing provides pin timing performance for each device density and speed grade. The data is typically used prior to designing the FPGA to get an estimate of the timing budget as part of the link timing analysis. The Quartus II Timing Analyzer provides a more accurate and precise I/O timing data based on the specifics of the design after you complete place-and-route.



The Excel-based I/O Timing spreadsheet will be available in the future release of the Quartus II software.

## Programmable IOE Delay

Table 2-41 lists the Cyclone V IOE programmable delay settings.

**Table 2-41. IOE Programmable Delay for Cyclone V Devices <sup>(1)</sup>**

Parameter	Available Settings	Minimum Offset	Fast Model		Slow Model			Unit
			Industrial	Commercial	C6 Speed Grade	C7, I7 Speed Grade	C8, A7 Speed Grade	
TBD	TBD	TBD	TBD	TBD	TBD	TBD	TBD	ns
TBD	TBD	TBD	TBD	TBD	TBD	TBD	TBD	ns
TBD	TBD	TBD	TBD	TBD	TBD	TBD	TBD	ns
TBD	TBD	TBD	TBD	TBD	TBD	TBD	TBD	ns
TBD	TBD	TBD	TBD	TBD	TBD	TBD	TBD	ns

Note to Table 2-41:

(1) Pending data extraction from the Quartus II software.

## Programmable Output Buffer Delay

Table 2-42 lists the delay chain settings that control the rising and falling edge delays of the output buffer. The default delay is 0 ps.

**Table 2-42. Programmable Output Buffer Delay for Cyclone V Devices—Preliminary <sup>(1), (2)</sup>**

Symbol	Parameter	Typical	Unit
D <sub>OUTBUF</sub>	Rising and/or falling edge delay	0 (default)	ps
		50	ps
		100	ps
		150	ps

Notes to Table 2-42:

- (1) Pending data extraction from the Quartus II software.
- (2) You can set the programmable output buffer delay in the Quartus II software by setting the **Output Buffer Delay Control** assignment to either positive, negative, or both edges, with the specific values stated here (in ps) for the **Output Buffer Delay** assignment.



# Glossary

Table 2-43 lists the glossary for this chapter.

Table 2-43. Glossary Table (Part 1 of 4)

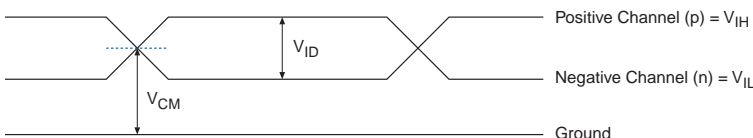
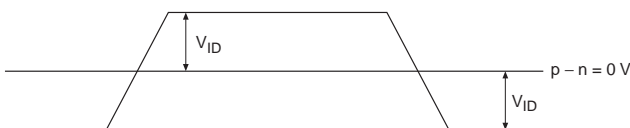
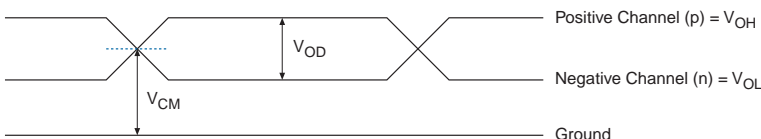
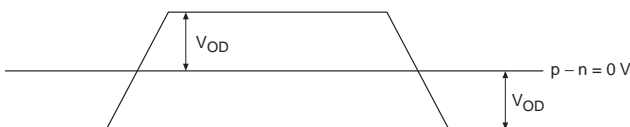
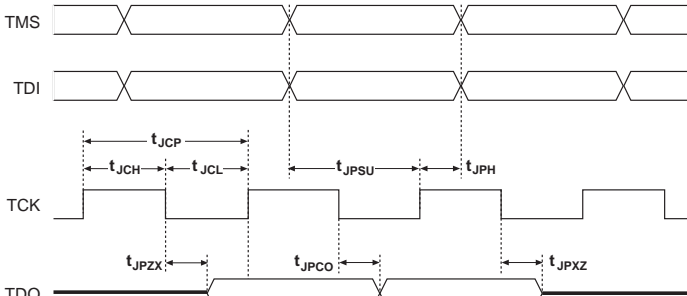
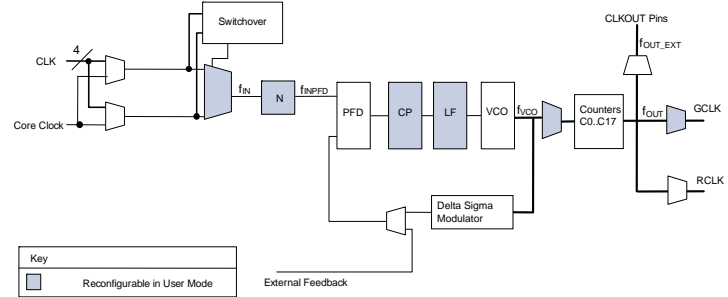
Letter	Subject	Definitions
A B C	—	—
D	Differential I/O Standards	<p><i>Receiver Input Waveforms</i></p> <p><b>Single-Ended Waveform</b></p>  <p>Positive Channel (p) = <math>V_{IH}</math> Negative Channel (n) = <math>V_{IL}</math> Ground</p> <p><b>Differential Waveform</b></p>  <p><math>p - n = 0\text{ V}</math></p> <p><i>Transmitter Output Waveforms</i></p> <p><b>Single-Ended Waveform</b></p>  <p>Positive Channel (p) = <math>V_{OH}</math> Negative Channel (n) = <math>V_{OL}</math> Ground</p> <p><b>Differential Waveform</b></p>  <p><math>p - n = 0\text{ V}</math></p>
E	—	—
F	$f_{HSCLK}$	Left/right PLL input clock frequency.
	$f_{HSDR}$	High-speed I/O block—Maximum/minimum LVDS data transfer rate ( $f_{HSDR} = 1/TUI$ ), non-DPA.
	$f_{HSDRDPA}$	High-speed I/O block—Maximum/minimum LVDS data transfer rate ( $f_{HSDRDPA} = 1/TUI$ ), DPA.
G H I	—	—

Table 2-43. Glossary Table (Part 2 of 4)

Letter	Subject	Definitions
<p><b>J</b></p>	<p>J</p>	<p>High-speed I/O block—Deserialization factor (width of parallel data bus).</p>
	<p>JTAG Timing Specifications</p>	<p>JTAG Timing Specifications:</p> 
<p><b>K</b> <b>L</b> <b>M</b> <b>N</b> <b>O</b></p>	<p>—</p>	<p>—</p>
<p><b>P</b></p>	<p>PLL Specifications</p>	<p><b>Diagram of PLL Specifications (1)</b></p>  <p><b>Note:</b> (1) Core Clock can only be fed by dedicated clock input pins or PLL outputs.</p>
<p><b>Q</b></p>	<p>—</p>	<p>—</p>
<p><b>R</b></p>	<p>R<sub>L</sub></p>	<p>Receiver differential input discrete resistor (external to the Cyclone V device).</p>

**Table 2-43. Glossary Table (Part 3 of 4)**

Letter	Subject	Definitions
S	Sampling window (SW)	<p>Timing Diagram—the period of time during which the data must be valid in order to capture it correctly. The setup and hold times determine the ideal strobe position within the sampling window, as shown:</p>
	Single-ended voltage referenced I/O standard	<p>The JEDEC standard for the <b>SSTI</b> and <b>HSTL</b> I/O defines both the AC and DC input signal values. The AC values indicate the voltage levels at which the receiver must meet its timing specifications. The DC values indicate the voltage levels at which the final logic state of the receiver is unambiguously defined. After the receiver input has crossed the AC value, the receiver changes to the new logic state.</p> <p>The new logic state is then maintained as long as the input stays beyond the AC threshold. This approach is intended to provide predictable receiver timing in the presence of input waveform ringing, as shown:</p> <p><i>Single-Ended Voltage Referenced I/O Standard</i></p>
T	$t_C$	High-speed receiver/transmitter input and output clock period.
	TCCS (channel-to-channel-skew)	The timing difference between the fastest and slowest output edges, including the $t_{C0}$ variation and clock skew, across channels driven by the same PLL. The clock is included in the TCCS measurement (refer to the <i>Timing Diagram</i> figure under <b>SW</b> in this table).
	$t_{DUTY}$	High-speed I/O block—Duty cycle on high-speed transmitter output clock. <b>Timing Unit Interval (TUI)</b> The timing budget allowed for skew, propagation delays, and the data sampling window. (TUI = 1/(Receiver Input Clock Frequency Multiplication Factor) = $t_C/w$ )
	$t_{FALL}$	Signal high-to-low transition time (80-20%)
	$t_{INCCJ}$	Cycle-to-cycle jitter tolerance on the PLL clock input
	$t_{OUTPJ\_IO}$	Period jitter on the general purpose I/O driven by a PLL
	$t_{OUTPJ\_DC}$	Period jitter on the dedicated clock output driven by a PLL
$t_{RISE}$	Signal low-to-high transition time (20-80%)	
U	—	—

**Table 2-43. Glossary Table (Part 4 of 4)**

Letter	Subject	Definitions
V	$V_{CM(DC)}$	DC common mode input voltage.
	$V_{ICM}$	Input common mode voltage—The common mode of the differential signal at the receiver.
	$V_{ID}$	Input differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.
	$V_{DIF(AC)}$	AC differential input voltage—Minimum AC input differential voltage required for switching.
	$V_{DIF(DC)}$	DC differential input voltage— Minimum DC input differential voltage required for switching.
	$V_{IH}$	Voltage input high—The minimum positive voltage applied to the input which is accepted by the device as a logic high.
	$V_{IH(AC)}$	High-level AC input voltage
	$V_{IH(DC)}$	High-level DC input voltage
	$V_{IL}$	Voltage input low—The maximum positive voltage applied to the input which is accepted by the device as a logic low.
	$V_{IL(AC)}$	Low-level AC input voltage
	$V_{IL(DC)}$	Low-level DC input voltage
	$V_{OCM}$	Output common mode voltage—The common mode of the differential signal at the transmitter.
	$V_{OD}$	Output differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter.
	$V_{SWING}$	Differential input voltage
	$V_X$	Input differential cross point voltage
$V_{OX}$	Output differential cross point voltage	
W	W	High-speed I/O block—Clock Boost Factor
X		
Y	—	—
Z		

## Document Revision History

Table 2-44 lists the revision history for this chapter.

**Table 2-44. Document Revision History**

Date	Version	Changes
February 2012	1.2	<ul style="list-style-type: none"> <li>■ Added automotive speed grade information.</li> <li>■ Added Figure 2-1.</li> <li>■ Updated Table 2-3, Table 2-8, Table 2-9, Table 2-20, Table 2-21, Table 2-22, Table 2-23, Table 2-24, Table 2-25, Table 2-26, Table 2-27, Table 2-28, Table 2-30, Table 2-35, and Table 2-41.</li> <li>■ Minor text edits.</li> </ul>
November 2011	1.1	<ul style="list-style-type: none"> <li>■ Added Table 2-5.</li> <li>■ Updated Table 2-3, Table 2-4, Table 2-11, Table 2-13, Table 2-20, and Table 2-21.</li> </ul>
October 2011	1.0	Initial release.





This chapter provides additional information about the document and Altera.

## How to Contact Altera

To locate the most up-to-date information about Altera products, refer to the following table.

Contact <sup>(1)</sup>	Contact Method	Address
Technical support	Website	<a href="http://www.altera.com/support">www.altera.com/support</a>
Technical training	Website	<a href="http://www.altera.com/training">www.altera.com/training</a>
	Email	<a href="mailto:custrain@altera.com">custrain@altera.com</a>
Product literature	Website	<a href="http://www.altera.com/literature">www.altera.com/literature</a>
Nontechnical support (general) (software licensing)	Email	<a href="mailto:nacomp@altera.com">nacomp@altera.com</a>
	Email	<a href="mailto:authorization@altera.com">authorization@altera.com</a>










**Note to Table:**

(1) You can also contact your local Altera sales office or sales representative.

## Typographic Conventions

The following table shows the typographic conventions this document uses.

Visual Cue	Meaning
<b>Bold Type with Initial Capital Letters</b>	Indicate command names, dialog box titles, dialog box options, and other GUI labels. For example, <b>Save As</b> dialog box. For GUI elements, capitalization matches the GUI.
<b>bold type</b>	Indicates directory names, project names, disk drive names, file names, file name extensions, software utility names, and GUI labels. For example, <code>\qdesigns</code> directory, <b>D:</b> drive, and <b>chiptrip.gdf</b> file.
<i>Italic Type with Initial Capital Letters</i>	Indicate document titles. For example, <i>Stratix IV Design Guidelines</i> .
<i>italic type</i>	Indicates variables. For example, $n + 1$ . Variable names are enclosed in angle brackets (< >). For example, <file name> and <project name>.pof file.
Initial Capital Letters	Indicate keyboard keys and menu names. For example, the Delete key and the Options menu.
“Subheading Title”	Quotation marks indicate references to sections in a document and titles of Quartus II Help topics. For example, “Typographic Conventions.”

Visual Cue	Meaning
Courier type	Indicates signal, port, register, bit, block, and primitive names. For example, <code>data1</code> , <code>tdi</code> , and <code>input</code> . The suffix <code>n</code> denotes an active-low signal. For example, <code>resetn</code> . Indicates command line commands and anything that must be typed exactly as it appears. For example, <code>c:\qdesigns\tutorial\chiptrip.gdf</code> . Also indicates sections of an actual file, such as a Report File, references to parts of files (for example, the AHDL keyword <code>SUBDESIGN</code> ), and logic function names (for example, <code>TRI</code> ).
	An angled arrow instructs you to press the Enter key.
1., 2., 3., and a., b., c., and so on	Numbered steps indicate a list of items when the sequence of the items is important, such as the steps listed in a procedure.
	Bullets indicate a list of items when the sequence of the items is not important.
	The hand points to information that requires special attention.
	The question mark directs you to a software help system with related information.
	The feet direct you to another document or website with related information.
	The multimedia icon directs you to a related multimedia presentation.
	A caution calls attention to a condition or possible situation that can damage or destroy the product or your work.
	A warning calls attention to a condition or possible situation that can cause you injury.
	The envelope links to the <a href="#">Email Subscription Management Center</a> page of the Altera website, where you can sign up to receive update notifications for Altera documents.



## Tema n. 2

La spettrometria di massa è considerata il "golden standard" tra le tecniche analitiche per l'identificazione di sostanze sconosciute. Da qualche anno, si è dimostrata la possibilità di superare la necessità di accoppiare tale tecnica con sistemi di separazione cromatografici, grazie all'impiego di Nano Electro Mechanical Systems (NEMS).

Il candidato progetti un sensore di massa completo per la diagnostica ambientale basato su micro/nano risonatori meccanici.

In particolare, motivando le proprie scelte anche con riferimenti quantitativi, si riporti:

- il principio di trasduzione del segnale da parte del sensore
- una tipica curva di taratura
- una o più figure di merito (sensibilità, precisione, ecc...)
- uno schematico complessivo e delle singole parti
- i passi di processo per la fabbricazione
- l'integrazione con l'elettronica di gestione
- l'eventuale microfluidica di interfacciamento

### Tema n. 3

Un condizionatore può essere rappresentato come una macchina in grado di:

- rilevare la temperatura ambientale  $T_a$
- ricevere e memorizzare una temperatura desiderata  $T_d$
- ricevere e memorizzare uno stato di attivazione e disattivazione;
- attivare o disattivare degli attuatori per soddisfare, nel tempo  $t$ , la disequazione  $|T_d - T_a| < \Delta$

In un'abitazione possono esserci più condizionatori.

Un proprietario può possedere più abitazioni.

Un'abitazione può avere più proprietari.

Un produttore di condizionatori desidera immettere sul mercato un sistema IoT per i propri apparati, rendendo possibile installare nelle abitazioni dei clienti un nuovo dispositivo connesso a internet, in grado di ricevere comandi per i condizionatori e inviare informazioni a un sistema centrale, consentendo ai proprietari di dialogare con i propri condizionatori - anche da remoto - tramite un client grafico (cruscotto).

Cruscotto ↔ Sistema centrale ↔ Dispositivo locale ↔ Condizionatori

Il candidato sviluppi - a sua scelta - almeno sei dei seguenti punti:

1. un diagramma entità-relazione del sistema locale;
2. un diagramma entità-relazione del sistema centrale;
3. il diagramma architetturale complessivo (cruscotto + centrale + locale) senza dettagliare le componenti interne;
4. i due diagrammi architetturali — dettagliando le componenti interne — del sistema centrale e del sistema locale;
5. un diagramma UML per una delle architetture summenzionate, per un aspetto a scelta;
6. un sequence diagram per una delle architetture summenzionate, per un aspetto a scelta;
7. lo pseudocodice di una componente critica a sua scelta relativo alla gestione del dispositivo locale;
8. un elenco — corredato dalle opportune giustificazioni — di quali linguaggi, sistemi operativi, protocolli e eventuali servizi terzi utilizzerebbe rispettivamente per il cruscotto, per il sistema centrale e per il dispositivo;
9. quali problemi di latenza possono essere presenti nel sistema e quali contromisure si potrebbero mettere in campo?
10. quali strategie potrebbero essere attuate per:
  - a. ridurre il consumo di banda?
  - b. trasmettere i dati in modo sicuro?
  - c. irrobustire i singoli sottosistemi ai disservizi per cause esterne o ai bug interni?
11. quali problemi di sicurezza si dovrebbero affrontare rispettivamente per il cruscotto, il sistema centrale e il dispositivo locale?
12. quali casi d'uso si potrebbero concepire per il cruscotto (relativamente al solo utente)?